



Data Acquisition Circuits

Data Conversion and DSP Analog Interface

Data Book

1995

Mixed-Signal Products

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Data Acquisition Circuits Data Book

Data Conversion and DSP Analog Interface



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INTRODUCTION

Texas Instruments offers an extensive line of industry-standard integrated circuits designed to provide highly reliable circuits for peripheral support applications of microprocessor-based systems, DSP (digital signal processing) related analog interfaces, video interfaces, video and high-speed converters, digitizing requirements that demand ADC and DAC conversion, and general-purpose functions.

TI data acquisition system circuits represent technologies from traditional bipolar through LinCMOS™, Advanced LinCMOS™, and LinEPIC™ processes. The LinCMOS™ and Advanced LinCMOS™ technologies feature improvements in resolution, power consumption, and temperature stability. LinEPIC™ has both improved conversion speed and reduced power consumption.

This data book provides information on the following types of products:

- Dual-Slope Analog-to-Digital Converters (ADC)
- Successive-Approximation Semi-Flash, and Flash ADC Converters
- Current Multiplying and Video DAC Converters
- High-Speed Converters for Control Applications
- Color Palette Chips for Computer Graphics
- Analog Interface Circuits for DSP Interface
- Switched-Capacitor Filter ICs
- Other General-Purpose Functions

These products cover the requirements of PC and workstation multimedia applications such as audio, graphics, communication applications, modems and cellular phones, video capture and image processing, industrial control and disk-drive servo-loop control, automotive, electronic instrumentation, consumer, digital audio and any DSP or microprocessor-based system. New surface-mount packages include both ceramic and plastic chip carriers, and the small-outline plastic packages that optimize board density with minimum impact on power-dissipation capability. The equipment with handlers and test equipment. In addition, specifications and programs are continuously updated. Quality and performance are monitored throughout all phases of manufacturing.

Included are those new products added to this volume as indicated by a dagger(†). The selection guide includes a functional description of each device by providing key parametric information and packaging options. Ordering information and mechanical data are in the last section of the book.

Complete technical data for all TI semiconductor products are available from your nearest TI Field Sales Office, local authorized TI distributor, or by writing directly to:

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We sincerely believe the new 1995 Data Acquisition Circuits Data Book will be a significant addition to your technical literature from Texas Instruments.

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†Product Preview

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†Product Preview

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†Product Preview

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†Product Preview

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1 General Information

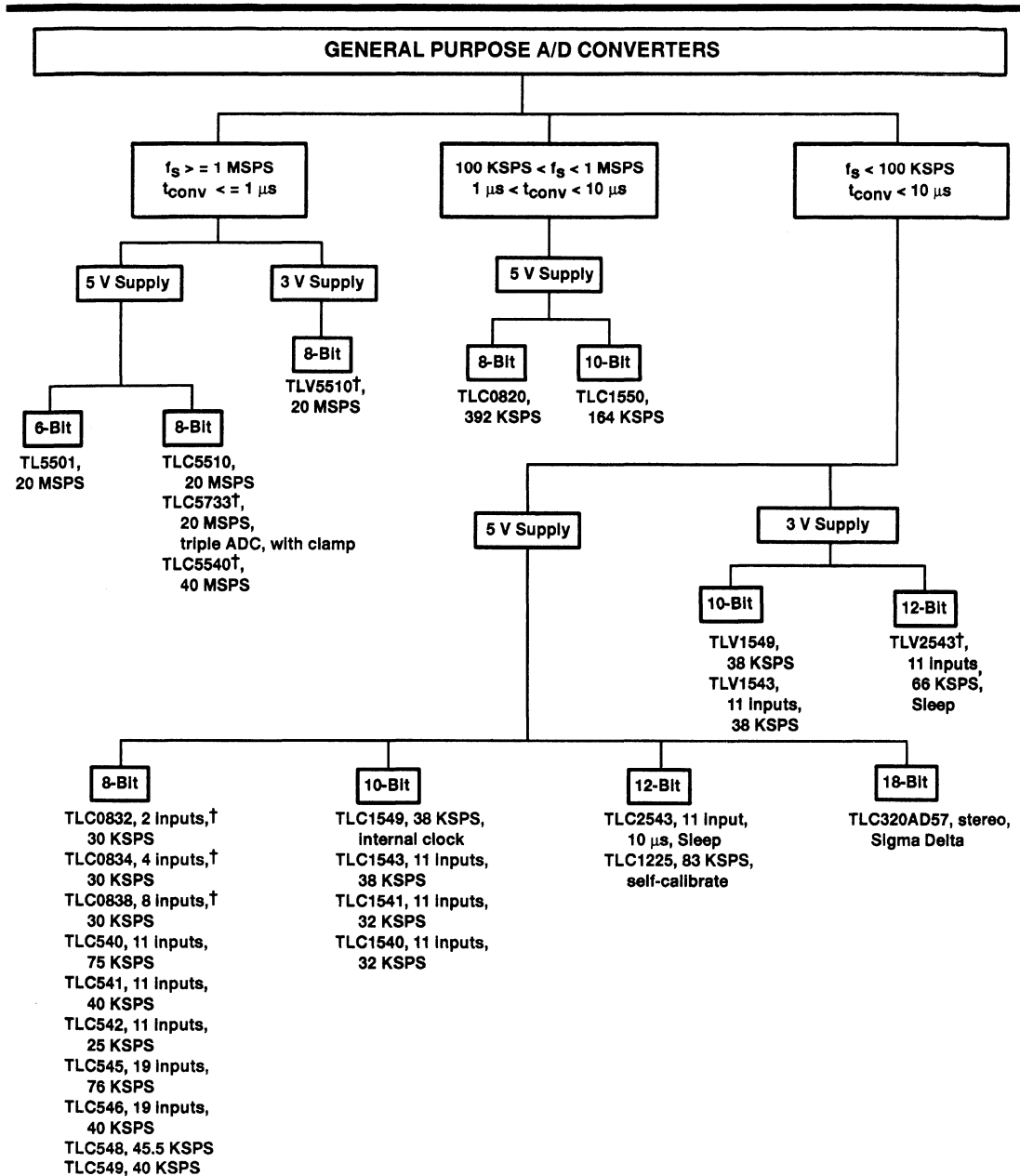
ANALOG-TO-DIGITAL CONVERTER SELECTION GUIDE

RESOLUTION	DEVICE	CONVERSION TIME (µs)	SAMPLING RATE (KSPS)	NUMBER OF CHANNELS	INTERNAL REFERENCE	SUPPLY VOLTAGE	PARALLEL OUTPUT	INTERNAL CLOCK	SHUTDOWN	POWER (mW max)	PACKAGE	NUMBER OF TERMINALS	COMMENTS
16/18	TLC320AD57		48, 44.1, 32	2	X	5		X	X	200	DW	28	Dual sigma-delta. SNR of 97 dB
12	TLC2543	10	66	11		5		X	X	12	DW, FN, N	20	Low cost, high resolution
	TLV2543†	10	66	11		3.3		X	X	8	DW, FN, N	20	3 V version TLC2543
	TLC1225/1125	12	83	1		±5	X			85	N, FN	28	Uni or bipolar with self-calibration
10	TLC1550/1551	6	164	1		5	X	X		40	FN, NW	24	DSP front end with 3-state outputs
	TLC1549	21	38	1		5		X		12	D, FK, JG, P	8	Plug in upgrade for TLC549
	TLV1549	21	38	1		3.3		X		8	D, FK, JG, P	8	3 V version TLC1549
	TLC1543	21	38	11		5		X		12	DW, FN, N	20	Plus in upgrade for TLC543
	TLV1543	21	38	11		3.3		X		8	DW, FK, J, N	20	3 V version TLC1543
	TLC1541	21	32	11		5				12	DW, J, N, FK, FN	20	±1 LSB total error
	TLC1540	21	32	11		5				12	DW, J, N, FK, FN	20	±0.5 LSB total error
	8	TLC5510		20,000	1		5	X			90	NS	24
TLV5510†			20,000	1		3	X			60	NS	24	3 V version of TLC5510
TLC5733†			20,000	3		5	X			375	QFP	64	Triple ADC with clamp
TLC5540††			40,000	1		5	X			120	NS	24	High speed ADC
TLC0820A		1.2	392	1		5	X	X		75	DW, F, NFK, N	20	Replaces AD7820 and ADC0820
TLC0838†		20		8		5				12	FN, N	20	Replaces ADC0838
TLC540		9	75	11		5				12	SW, N, FN	20	Replaces ADC0811 and MC145040
TLC541		17	40	11		5				12	DW, N, FN	20	Compatible with TLC1540 pinout
TLC542		20	25	11		5		X		10	FN, N, DW	20	Replaces MC145041
TLC545		9	76	19		5				12	FN, N	28	µP compatible
TLC546		17	40	19		5				12	FN, N	28	µP compatible
TLC548		17	45.5	1		5		X		12	D, P	8	µP compatible
TLC549		17	40	1		5		X		12	D, P	8	µP compatible

† Budgetary pricing for 0°C to 70°C

† Indicates product preview

ANALOG-TO-DIGITAL CONVERTER SELECTION GUIDE



† Indicates product preview status at time of print.

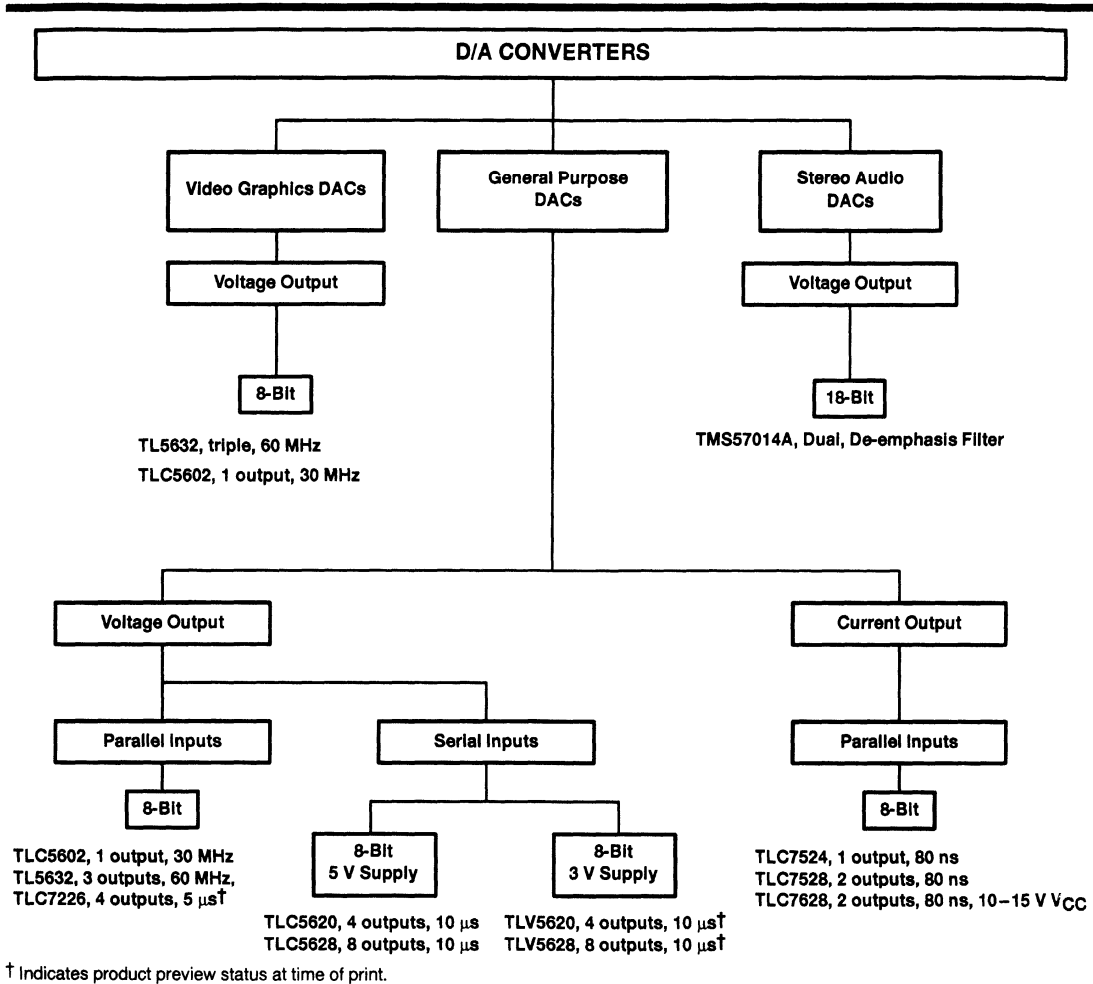
DIGITAL-TO-ANALOG CONVERTER SELECTION GUIDE

RESOLUTION	DEVICE	BUS INTERFACE		OUTPUT (I OR V)		NO. OF DAC's	REFERENCE†	SETTLING TIME	SUPPLY VOLTAGE (V)	LINEARITY (LSB)	CONVERSION RATE	POWER (mW max)	PACKAGE	NO. OF PINS	COMMENTS
16/18	TMS57014A	Serial	PWM	2	N/A			5		32, 37.8, 44.1 and 48 kHz	350	DWB	28	Dual audio sigma-delta DAC with interpolation filter and digital volume control	
8	TLC7524	8, μ P	I	1	Ext, M	100 ns	5-15	± 0.5			5	D,N,FN	16	Popular low cost MDAC with latch for DSP and μ 's	
	TLC7528	8, μ P	I	2	Ext, M	100 ns	5-15	± 0.5			5	DW,N, FN	20	Dual version of TLC7524	
	TLC7628	8, μ P	I	2	Ext, M	100 ns	10-15	± 0.5			20	DW,N, FN	20	Dual MDAC with TTL-compatible inputs	
	TLC7225‡	8, μ P	V	4	Ext	5 μ s		± 0.5						Separate reference for each DAC	
	TLC7226‡	8, μ P	V	8	Ext	5 μ s		± 0.5			195	DW,N, FN	20	Replaces AD7226	
	TLC5620	Serial	V	4	Ext	10 μ s	5	± 1			10	N,D	14	Low power quad DAC with programmable x1 or x2 output.	
	TLC5628	Serial	V	8	Ext	10 μ s	5	± 1			10	N,DW	16	Low power, octal DAC with programmable x1 or x2 output.	
	TLV5620‡	Serial	V	4	Ext	10 μ s	3	± 1			10	N,D	14	3 V version of TLC5620	
	TLV5628‡	Serial	V	8	Ext	10 μ s	3	± 1			10	N,D	16	3 V version of TLV5628	
	TLC5602	8	V	1	Ext	30 ns	5	± 0.5	30 MHz		80	N,DW	18	Low power video DAC	
TL5632	8 by 3	V	3	Int		5	± 0.5	60 MHz		350	FR	44	Triple video DAC with internal reference.		

† Ext, M – external reference, multiplying; PWM – Pulse width modulated

‡ Indicates product preview

DIGITAL-TO-ANALOG CONVERTER SELECTION GUIDE



DATA ACQUISITION AND CONVERSION CROSS-REFERENCE GUIDE

Replacements are based on similarity of electrical and mechanical characteristics shown in currently published data. Interchangeability in particular applications is not guaranteed. Before using a device as a substitute, compare the specifications of the substitute device with the specifications of the original.

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Manufacturers are arranged in alphabetical order.

ANALOG DEVICES	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
AD573		TLC1550INW TLC1550IFN TLC1551INW TLC1551IFN TLC7524IN TLC7524CN TLC7528IN TLC7528CN
AD7524AD	AD7524AN	
AD7524JN	AD7524JN	
AD7528BQ	AD7528BN	
AD7528KN	AD7528KN	
AD7820K/B/T	TLC0820A	
AD7820L/C/U		
AD7820	TLC0820	
AD7890		TLC2543IN TLC2543IDW TLV2543IN (3V) TLV2543IDW
ADC82AG		
AD82AM		TLC0820AIN
AD1878		TLC320AD57
AD9048		TLC5540INS
ADC-EK12DC		TLC7135CN TLC7135CFN ICL7135CN ICL7135CFN
ADC-EK12DR		TLC7135CN TLC7135CFN ICL7135CN ICL7135CFN
PM7524FQ		TLC7524IN, AD7524AN
PM7524FP		TLC7524CN, AD7524JN
PM7528		TLC7528, AD7528
BROOKTREE	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
Bt101, 102, 253		TL5632CFR
CRYSTAL	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
5336, 5339		TLC320AD57

DATA ACQUISITION AND CONVERSION CROSS-REFERENCE GUIDE

FUJITSU	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
MB40576	TL5501	
MB40578	TLC5502	TLV5510 (3 V)
MB40778	TLC5602	
HARRIS	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
HI1175		TLV5510INS (3 V)
LINEAR TECHNOLOGY	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
LTC1091		TLC1549IN TLC1549IDW
LTC1092/93/94		TLC1542IN TLC1543IN TLC1542IDW TLC1543IDN TLC2543IDW
LTC1291/92/93/94		
MAXIM	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
MAX17x Family		TLC2543IN TLC2543IDW TLC2543IFN TLC2543 (3V) TLC5620 TLC5628
MAX509		
MAX529		
MICRO NETWORKS	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
MN5100/5101		TLC0820ACN TLC0820ACN
MN5120/5130/5140		
MICRO POWER SYSTEMS	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
MP7138AN		TLC7135CN TLC7135CFN ICL7135CN ICL7135CFN



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MOTOROLA	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
MC14433P		TLC7135CN TLC7135CFN ICL7135CN ICL7135CFN
MC14444P		TLC546IN
MC145040FN	TLC541MFN	TLC540MFN
MC145040L	TLC541MJ	TLC540MJ
MC145040P	TLC541MN	TLC540MN
MC145041P1	TLC542IN	
MC14051		TLC1543IN TLC1542IN TLC1543IDW TLC1542IDW

NATIONAL	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
ADC0811BCJ	TLC541IN	TLC540IN
ADC0811BCN	TLC541IFN	TLC540IFN
ADC0811BJ	TLC541MJ	TLC540MJ
ADC0811CCJ	TLC541IN	TLC540IN
ADC0811CCN	TLC541IN	TLC540IN
ADC0811CCV	TLC541IFN	TLC540IFN
ADC0811CJ	TLC541MJ	TLC540MJ
ADC0820BCD	TLC0820BIN	
ADC0820BCN	TLC0820BCN	
ADC0820BD	TLC0820BMJ	
ADC0820CCD	TLC0820AIN	
ADC0820CCN	TLC0820ACN	
ADC0820CD	TLC0820AMJ	
ADC0830BCN		TLC546IN
ADC0830CCN		TLC546IN
ADC0831BCJ	TLC0831BIP	TLC549IN
ADC0831BCN	TLC0831BIP	TLC549IN
ADC0831CCJ	TLC0831AIP	TLC549IN
ADC0831CCN	TLC0831ACP	TLC549IN
ADC0832BCJ	TLC0832BIP	
ADC0832BCN	TLC0832BCP	
ADC0832CCJ	TLC0832AIP	
ADC0832CCN	TLC0832ACP	
ADC0834BCJ		TLC0834BIN
ADC0834BCN		TLC0834BCN
ADC0834CCJ		TLC0834AIN
ADC0834CCN		TLC0834ACN
ADC0838BCJ		TLC0838BIN
ADC0838BCN		TLC0838BCN
ADC0838CCJ		TLC0838AIN

DATA ACQUISITION AND CONVERSION CROSS-REFERENCE GUIDE

NATIONAL (Continued)	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
ADC0838CCN		TLC0838ACN
ADC1001CCJ		TLC1541IN
ADC1005BCJ		TLC1541IN
ADC1005CCJ		TLC1541IN
ADC1225		TLC1225
ADC3511CCN		TLC7135CN
		ICL7135CN
ADC3711CCN		TLC7135CN
		TLC7135CFN
		ICL7135CN
		ICL7135CFN
MF4-50	TLC04/MF4A-50	
MF4-100	TLC14/MF4A-100	
PHILLIPS	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
NE5036FE/N/D		TLC549CN/CD
NE5037F/N/D		TLC549CN/CD
TDA8703		TLC5540INS
TDA8707		TLC5733IPM
SILICONIX	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
LD110CJ		TLC7135N
		ICL7135CN
LD111ACJ		TLC7135CN
		ICL7135CN
LD120CJ		TLC7135CN
		ICL7135CN
LD121ACJ		TLC7135CN
		ICL7135CN
Si7135CJ	TLC7135CN	
	ICL7135CN	
SONY	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
CXD1175		TLC5510INS
		TLV5510INC (3V)
CXD1179		TLC5540INS

DATA ACQUISITION AND CONVERSION CROSS-REFERENCE GUIDE

TELEDYNE	DIRECT TI REPLACEMENT	SUGGESTED TI REPLACEMENT
TSC7135CPI	TLC7135CN ICL7135CN	
TSC8701		TLC1541IN
TSC8704		TLC1541IN
TSC14433CN		TLC7135CN ICL7135CN



DEVICES DISCONTINUED SINCE 1992 DATA BOOK

Analog-to-Digital Converters

ADC0803	ADC0832	TL502	TLC5502-5
ADC0804	ADC0834	TL503	TLC5503-2
ADC0805	ADC0838	TL505	TLC5503-5
ADC0808	TLC532/3	TL507	TL5501
ADC0809	TL500	ADC0820†	
ADC0831	TL501	TLC5502-2	

† Retaining the TLC0820A

Analog Interface Circuits

TLC32071
TLC32042

Analog Switches‡

TL181	TL191	TL607	TLC4066
TL185	TL601	TL610	
TL188	TL604	TLC4016	

‡ All analog switches and multiplexers in the data book are discontinued.

Filters

MF10A
MF10C
TLC10
TLC20

**TERMS, DEFINITIONS, AND LETTER SYMBOLS FOR
ANALOG-TO-DIGITAL AND DIGITAL-TO-ANALOG CONVERTERS**

INTRODUCTION

These terms, definitions, and letter symbols are in accordance with those currently approved by the JEDEC Council of the Electronic Industries Association (EIA) for use in the USA and by the International Electrotechnical Commission (IEC) for international use.

1. GENERAL TERMS

Analog-to-Digital Converter (ADC)

A converter that uniquely represents all analog input values within a specified total input range by a limited number of digital output codes, each of which exclusively represents a fractional part of the total analog input range (see Figure 1).

NOTE: This quantization procedure introduces inherent errors of one-half LSB (least significant bit) in the representation since, within this fractional range, only one analog value can be represented free of error by a single digital output code.

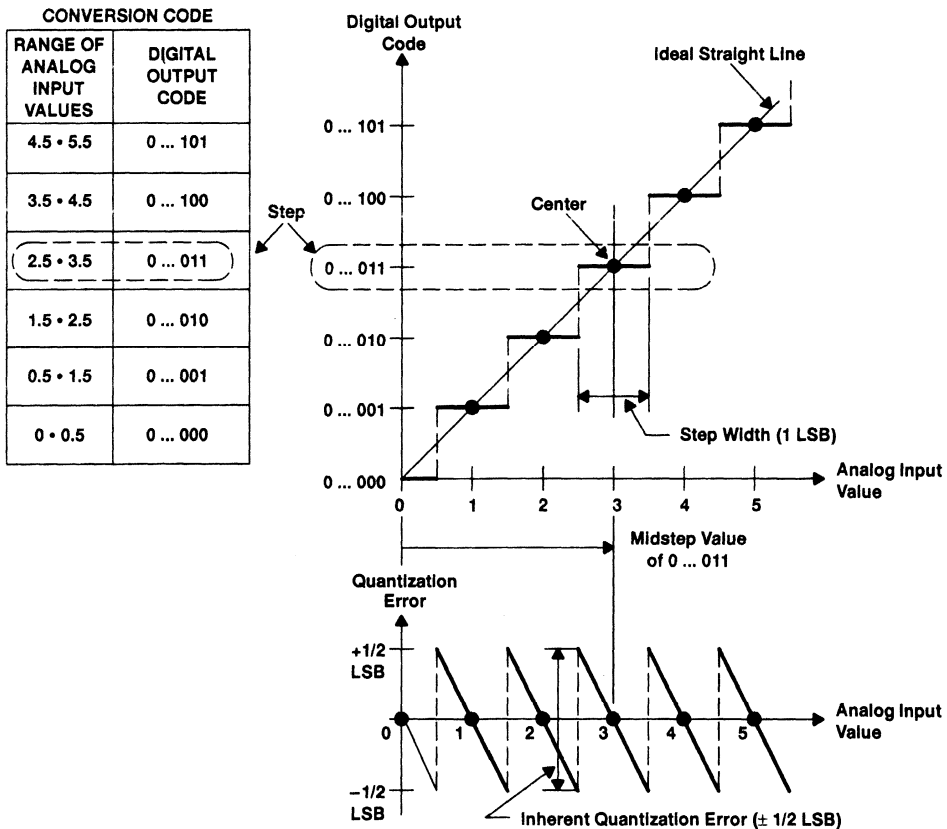


Figure 1. Elements of Transfer Diagram for an Ideal Linear ADC

GLOSSARY TERMS, DEFINITIONS AND LETTER SYMBOLS

Analog-to-Digital Processor

An integrated circuit providing the analog part of an ADC; provision of external timing, counting, and arithmetic operations is necessary for implementing a full analog-to-digital converter.

Companding DAC

A DAC whose transfer function complies with a compression or expansion law.

NOTE 1: The corresponding ADC normally consists of such a companding DAC and additional external circuitry.

NOTE 2: The compression or expansion law is usually a logarithmic function, e.g., A-law or μ -law.

Conversion Code (of an ADC or a DAC)

The set of correlations between each of the fractional parts of the total analog input range or each of the digital input codes, respectively, and the corresponding digital output codes or analog output values, respectively (see Figures 1 and 2).

NOTE: Examples of output code formats are straight binary, 2's complement, and binary-coded decimal.

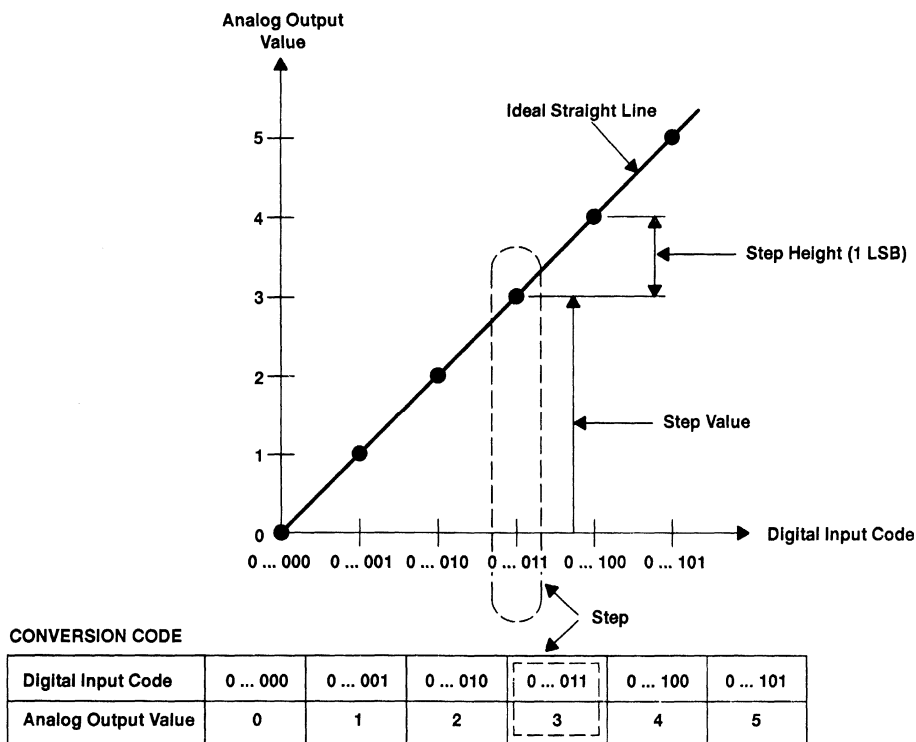


Figure 2. Elements of Transfer Diagram for an Ideal Linear DAC

Digital-to-Analog Converter (DAC)

A converter that represents a limited number of different digital input codes by a corresponding number of discrete analog output values (see Figure 2)

NOTE: Examples of input code formats are straight binary, 2's complement, and binary-coded decimal.

Full Scale (of a unipolar ADC or DAC)

A term used to refer a characteristic to that step within the transfer diagram whose nominal midstep value or nominal step value has the highest absolute value [see Figure 3(a) for a linear unipolar ADC].

NOTE 1: The subscript for the letter symbol of a characteristic at full scale is FS.

NOTE 2: In place of a letter symbol, the abbreviation FS is in common use.

Full Scale, Negative (of a bipolar ADC or DAC) [see Figures 3(b) and 3(c)]

A term used to refer a characteristic to the negative end of the transfer diagram, that is, to the step whose nominal midstep value or nominal step value has the most-negative value.

NOTE 1: The subscript for the letter symbol of a characteristic at negative full scale is FS⁻ (V_{FS-} , I_{FS-}).

NOTE 2: In place of a letter symbol, the abbreviation FS⁻ is in common use.

Full Scale, Positive (of a bipolar ADC or DAC) [see Figure 3(b) and 3(c)]

A term used to refer a characteristic to the positive end of the transfer diagram, that is, to the step whose nominal midstep value or nominal step value has the most-positive value.

NOTE 1: The subscript for the letter symbol of a characteristic at positive full scale is FS⁺ (V_{FS+} , I_{FS+}).

NOTE 2: In place of a letter symbol, the abbreviation FS⁺ is in common use.

Full-Scale Range, Nominal (of a linear ADC or DAC) (V_{FSRnom} , I_{FSRnom}) (see Figure 3)

The total range in analog values that can be coded with uniform accuracy by the total number of steps with this number rounded to the next higher power of 2.

NOTE: In place of the letter symbols, the abbreviation FSR(nom) can be used.

Example: Using a straight binary n-bit code format, it follows:

- for an ADC: $FSR(nom) = 2^n \times (\text{nominal value of step width})$
- for a DAC: $FSR(nom) = 2^n \times (\text{nominal value of step height})$

Full-Scale Value, Nominal (V_{FSnom} , I_{FSnom})

A value derived from the nominal full-scale range:

- for a unipolar converter: $V_{FSnom} = V_{FSRnom}$
- for a bipolar converter: $V_{FSnom} = 1/2 V_{FSRnom}$ (see Figure 3)

NOTE 1: In a few data sheets, this analog value is used as a reference value for adjustment procedures or as a rounded value for the full-scale range(s).

NOTE 2: In place of letter symbols, the abbreviation FS(nom) is in common use.

Full-Scale Range, (Practical) (of a linear ADC or DAC) (V_{FSR} , I_{FSR}) (V_{FSRpr} , I_{FSRpr}) (see Figure 3)

The total range of analog values that correspond to the ideal straight line.

NOTE 1: The qualifying adjective practical can usually be deleted from this term provided that, in a very few critical cases, the term nominal full-scale range is not also shortened in the same way. This permits use of the shorter letter symbols or abbreviations (see Note 2).

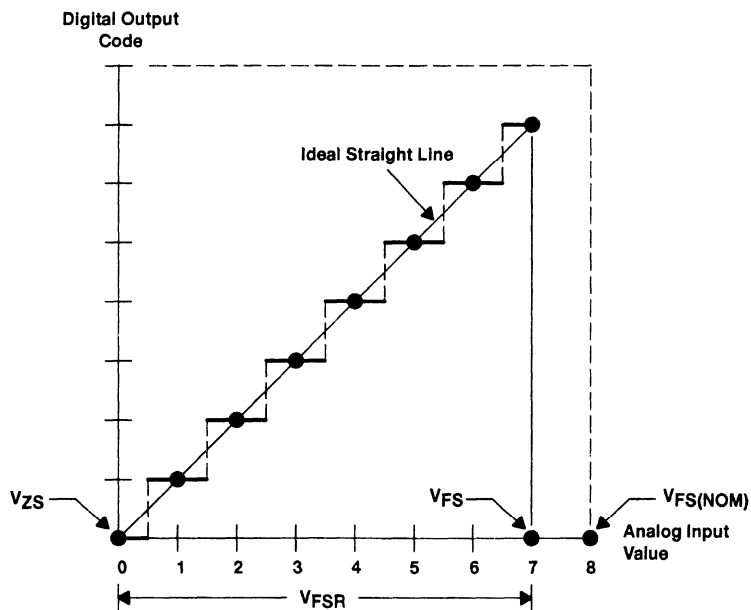
NOTE 2: In place of the letter symbols, the abbreviations FSR and FSR(pr) are in common use.

NOTE 3: The (practical) full-scale range has only a nominal value because it is defined by the end points of the ideal straight line.

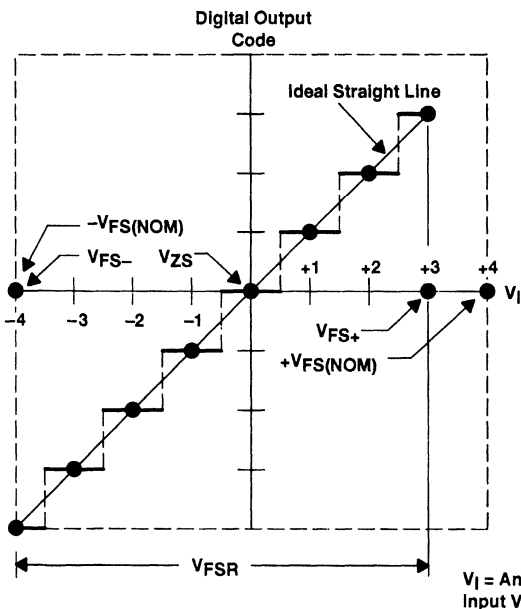
Example: Using a straight binary n-bit code format, it follows:

- for an ADC: $FSR = (2^n - 1) \times (\text{nominal value of step width})$
- for a DAC: $FSR = (2^n - 1) \times (\text{nominal value of step height})$

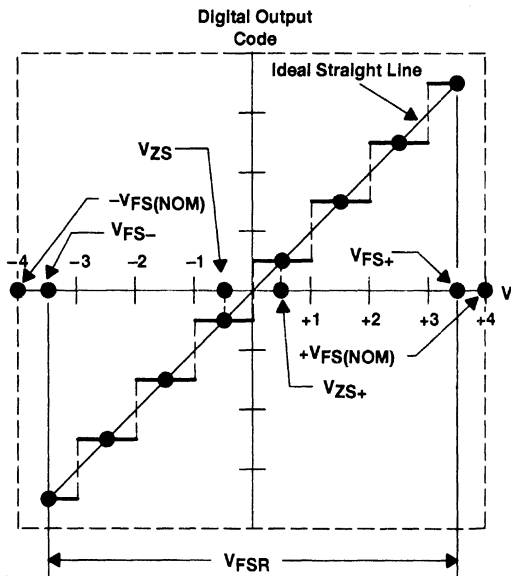
GLOSSARY TERMS, DEFINITIONS AND LETTER SYMBOLS



(a) UNIPOLAR ADC



(b) BIPOLAR ADC WITH TRUE ZERO



(c) BIPOLAR ADC WITH NO TRUE ZERO

Figure 3. Ideal Straight Line, Full-Scale Value and Zero-Scale Value
(Shown for Ideal Linear ADCs)

Gain Point (of an adjustable ADC or DAC)

The point in the transfer diagram corresponding to the midstep value (for an ADC) or the step value (for a DAC) of the step for which gain error is specified (usually full scale), and in reference to which the gain adjustment is performed (see Figures 4 and 5).

NOTE: Gain adjustment causes only a change of the slope of the transfer diagram, without changing the offset error.

Ideal Straight Line (of a linear ADC or DAC)

In the transfer diagram, a straight line between the specified points for the most-positive (least-negative) and most-negative (least-positive) nominal midstep values or nominal step values, respectively (see Figures 1, 2, and 3).

NOTE: The ideal straight line passes through all the points for nominal midstep values or nominal step values, respectively.

Linear ADC

An ADC having steps ideally of equal width excluding the steps at the two ends of the total range of analog input values.

NOTE: Ideally, the width of each end steps is one half of the width of any other step (see Figure 1).

Linear DAC

A DAC having steps ideally of equal height (see Figure 2).

LSB, Abbreviation

The abbreviation for Least Significant Bit, that is, for the bit that has the lowest positional weight in a natural binary numeral.

Example: In the natural binary numeral 1010, the rightmost bit 0 is the LSB.

LSB, Unit Symbol (for linear converters only)

The unit symbol for the magnitude of the analog resolution of a linear converter, which serves as a reference unit to express the magnitude of other analog quantities of that same converter, especially of analog errors, as multiples or submultiples of the magnitude of the analog resolution.

Example: 1/2 LSB means an analog quantity equal to 0.5 times the analog resolution.

NOTE: The unit symbol LSB refers to the fact that, for a natural binary code, the analog resolution corresponds to the nominal positional weight attributed to the least significant bit of the binary numeral.

In this case, the identity:

$$1 \text{ LSB} = \text{analog resolution}$$

leads, for an n-bit resolution, to:

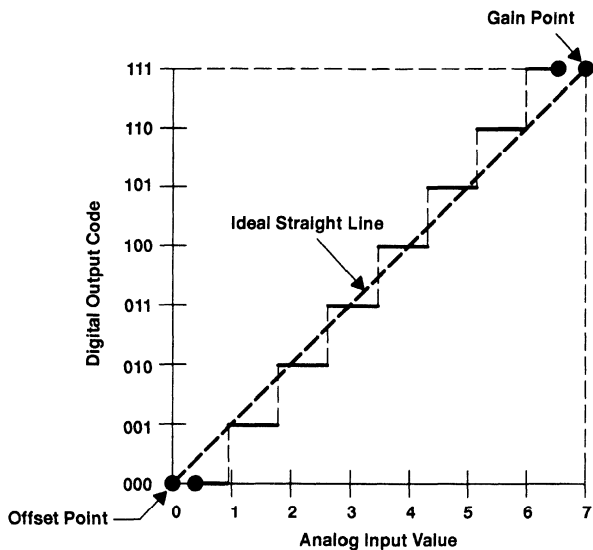
$$1 \text{ LSB} = \frac{\text{FSR}}{2^n - 1} = \frac{\text{FSR}(\text{nom})}{2^n}$$

Midstep Value (of an ADC)

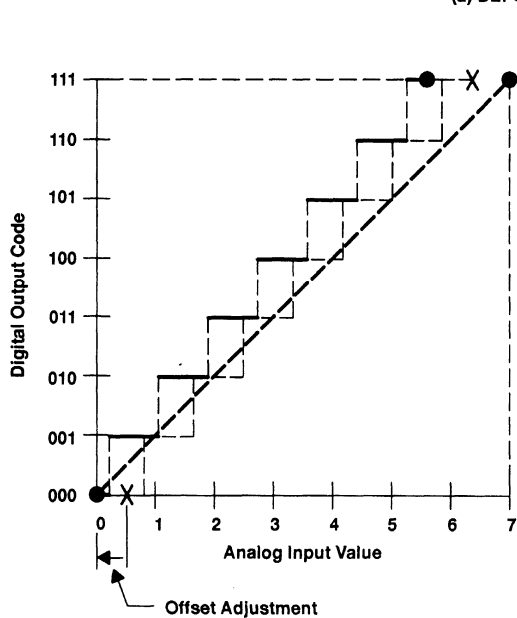
The analog value for the center of the step excluding the steps at the two ends of the total range of analog input values.

NOTE: For the end steps, the midstep value is defined as the analog value that results when the analog value for the transition to the adjacent step is reduced or enlarged, as appropriate, by half the nominal value of the step width (see Figure 1).

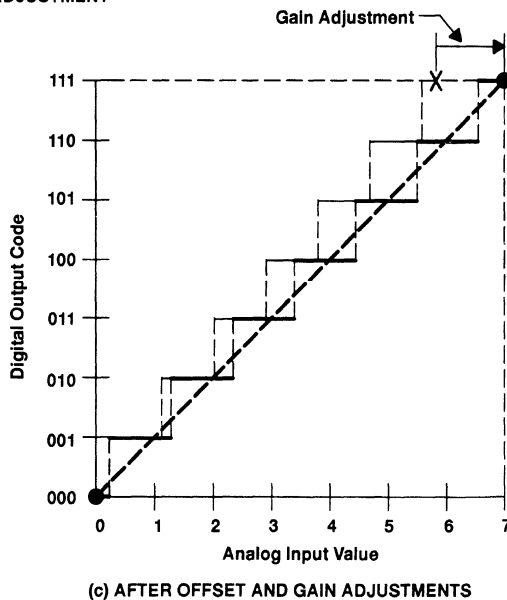
GLOSSARY TERMS, DEFINITIONS AND LETTER SYMBOLS



(a) BEFORE ADJUSTMENT



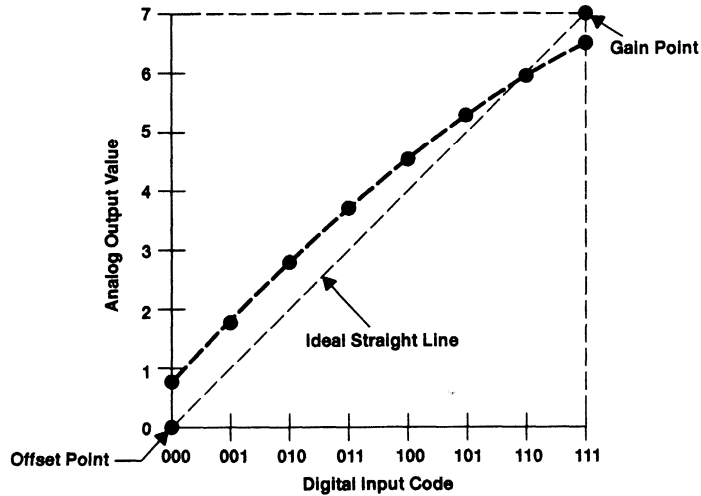
(b) AFTER OFFSET ADJUSTMENT



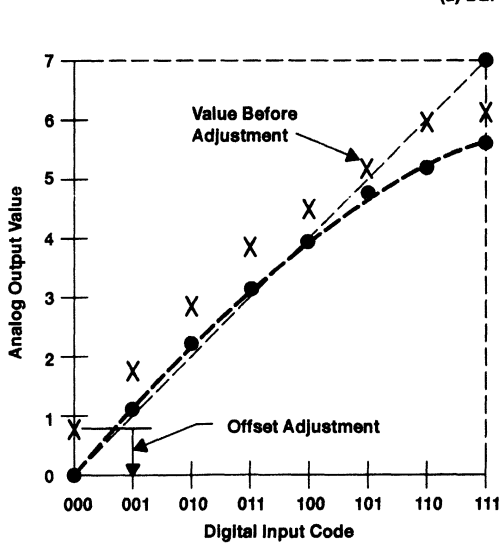
(c) AFTER OFFSET AND GAIN ADJUSTMENTS

NOTE A: In the above examples, the offset point is referred to the step with the digital code 000, and the gain point is referred to the step with the digital code 111.

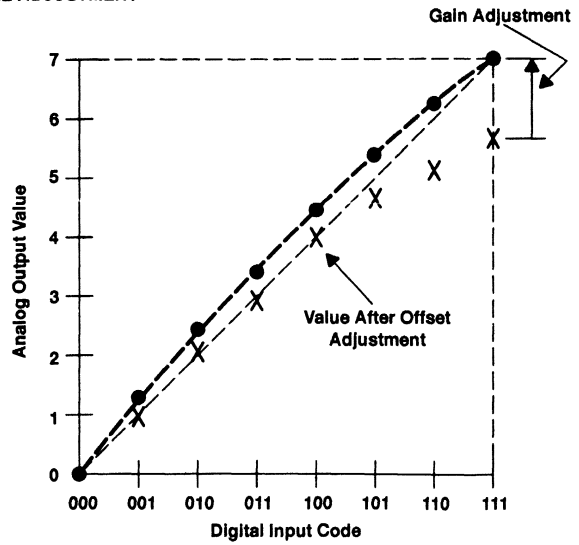
Figure 4. Adjustment in Offset Point and Gain Point for an ADC



(a) BEFORE ADJUSTMENT



(b) AFTER OFFSET ADJUSTMENT



(c) AFTER OFFSET AND GAIN ADJUSTMENTS

NOTE A: In the above examples, the offset point is referred to the step with the digital code 000, and the gain point is referred to the step with the digital code 111.

Figure 5. Adjustment In Offset and Gain Point for a DAC

Midstep Value, Nominal (of an ADC)

A specified analog value within a step that is ideally represented free of error by the corresponding digital output code (see Figure 1).

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TERMS, DEFINITIONS AND LETTER SYMBOLS

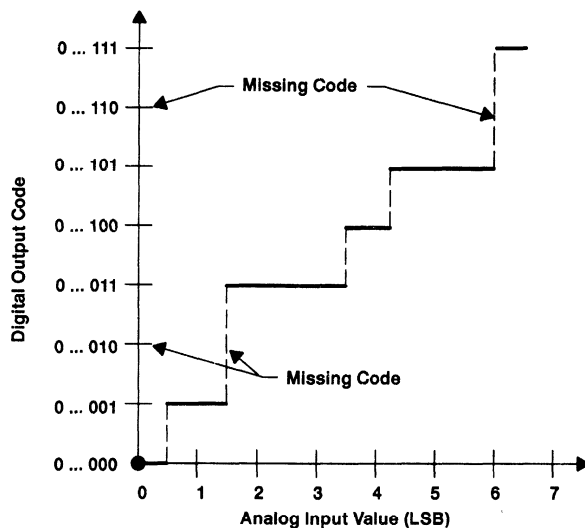


Figure 6. Missing Code for an ADC

Missing Code (of an ADC)

An intermediate code that is absent when the changing analog input to an ADC causes a multiple code change in the digital output (see Figure 6).

Monotonicity (of an ADC or a DAC)

A property of the transfer function that ensures the consistent increase or decrease of the analog output of a DAC or the digital output of an ADC in response to a consistent increase or decrease of the digital or analog input, respectively (Figure 7 illustrates nonmonotonic conversion).

NOTE: An intermediate increment with the value of zero does not invalidate monotonicity.

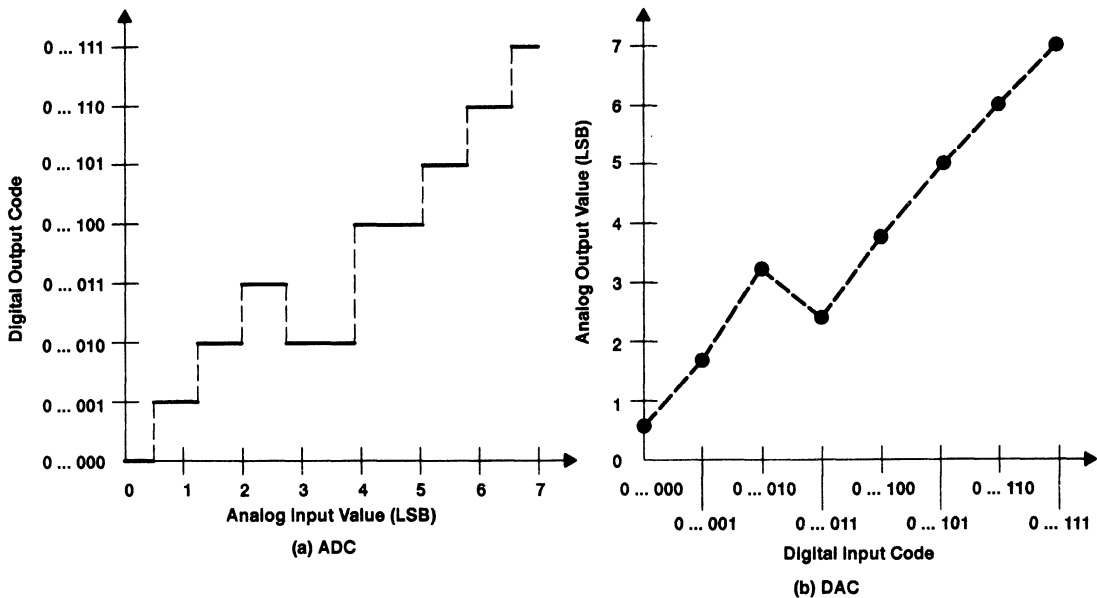


Figure 7. Nonmonotonic Conversion of an ADC or DAC

Multiplying DAC

A DAC having at least two inputs, at least one of which is digital, and whose analog output value is proportional to the product of the inputs.

Nonlinear ADC or DAC

An ADC or a DAC with a specified nonlinear transfer function between the nominal midstep values or nominal step values, respectively, and the corresponding step widths or step heights, respectively.

NOTE: The function may be continuously nonlinear or piece-wise linear.

Offset Point (of an adjustable ADC or DAC)

The point in the transfer diagram corresponding to the midstep value (for an ADC) or the step value (for a DAC) of the step about which the transfer diagram rotates when gain is adjusted (see Figures 4 and 5).

NOTE: Offset adjustment must be performed with respect to this point so that it causes only a parallel displacement of the transfer diagram, without changing its slope.

Resolution (general term)

NOTE 1: Resolution as a capability can be expressed in different forms: (see resolution, analog, resolution, numerical, and resolution, relative).

NOTE 2: Resolution is a design parameter and therefore has only a nominal value.

NOTE 3: The terms for these different forms may all be shortened to resolution if no ambiguity is likely to occur (for example, when the dimension of the term is also given).

Resolution (of an ADC)

The degree to which nearly equal values of the analog input quantity can be discriminated.

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TERMS, DEFINITIONS AND LETTER SYMBOLS

Resolution (of a DAC)

The degree to which nearly equal values of the analog output quantity can be produced.

Resolution, Analog (of a linear or nonlinear ADC or DAC)

For an ADC: The nominal value of the step width.

For a DAC: The nominal value of the step height.

NOTE: For a linear ADC or DAC, the constant magnitude of the analog resolution is often used as the reference unit LSB.

Resolution, Numerical

The number (n) of digits in the chosen numbering system necessary to express the total number of steps.

NOTE 1: The numbering system is normally a binary or a decimal system.

NOTE 2: In the binary-coded-decimal numbering system, the term 1/2 digit refers to an additional decimal digit with the highest positional value, but limited to the decimal figures 0 or 1 as it is represented by only a single bit. This additional digit serves to double the range of values covered by the other n digits.

Resolution, Relative (of a Linear ADC or DAC)

The ratio of the analog resolution to the full-scale range (practical or nominal).

NOTE: This ratio is normally expressed as a percentage of the full-scale range [% of FSR, % of FSR(nom)]. For high resolutions (high value of n), it is of little importance whether this ratio refers to the practical or nominal full-scale range.

Step (of an analog-to-digital or digital-to-analog conversion)

In the conversion code: Any of the individual correlations.

In the transfer diagram: Any part of the diagram equating to an individual correlation.

For an ADC, a step represents both a fractional range of analog input values and the corresponding digital output code (see Figure 1).

For a DAC, a step represents both a digital input code and the corresponding discrete analog output value (see Figure 2).

Step Height (Step Size) (of a DAC)

The absolute value of the difference in step value between two adjacent steps in the transfer diagram. (see Figure 2).

NOTE: For companding DACs, the term step size is in general use.

Step Value (of a DAC)

The value of the analog output representing a digital input code (see Figure 2).

Step Value, Nominal (of a DAC)

A specified step value that represents free of error the corresponding digital input code (see Figure 2).

Step Width (of an ADC)

The absolute value of the difference between the two ends of the range of analog values corresponding to one step (see Figure 1).

Temperature Coefficients of Analog Characteristics (α)

NOTE 1: The letter symbol for the temperature coefficient of an analog characteristic consists of the letter symbol α with a subscript referring to the relevant characteristic.

Example: Temperature coefficient of the gain error: α_{EG}

NOTE 2: Temperature coefficients are usually specified in parts per million (relative to the full-scale value) per degrees Celsius, that is, in ppm/°C.

Zero Scale (of an ADC or a DAC with true zero) [see Figures 3(a) and 3(b)]

A term used to refer a characteristic to the step whose nominal midstep value or nominal step value equals zero.

NOTE 1: The subscript for the letter symbol of a characteristic at zero scale is ZS.

NOTE 2: In place of a letter symbol, the abbreviation ZS is in common use.

Zero Scale, Negative (of an ADC or a DAC with no true zero) [see Figure 3(c)]

A term used to refer a characteristic to the negative step closest to analog zero.

NOTE 1: The subscript for the letter symbol of a characteristic at negative zero scale is ZS⁻ (V_{ZS-} , I_{ZS-}).

NOTE 2: In place of a letter symbol, the abbreviation ZS⁻ is in common use.

Zero Scale, Positive (of an ADC or a DAC with no true zero) [see Figure 3(c)]

A term used to refer a characteristic to the positive step closest to analog zero.

NOTE 1: The subscript for the letter symbol of a characteristic at positive zero scale is ZS⁺ (V_{ZS+} , I_{ZS+}).

NOTE 2: In place of a letter symbol, the abbreviation ZS⁺ is in common use.

2. STATIC PERFORMANCE

Accuracy (see Errors, Part 4)

Asymmetry, Full-Scale (of a DAC with a bipolar analog range) (ΔI_{FSS} , ΔV_{FSS})

The difference between the absolute values of the two full-scale analog values.

Compliance, Current (of a DAC) ($I_{O(op)}$)

The permissible range of output current within which the specifications are valid.

Compliance, Voltage (of a DAC) ($V_{O(op)}$)

The permissible range of output voltage within which the specifications are valid.

Error (see Part 4)

Supply Voltage Sensitivity, (of a DAC) (k_{SVS})

The change in full scale output current (or voltage) caused by a change in supply voltage.

NOTE: This sensitivity is usually expressed as the ratio of the percent change of full-scale current (or voltage) to the percent change of supply voltage.

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TERMS, DEFINITIONS AND LETTER SYMBOLS

3. DYNAMIC PERFORMANCE

Conversion Rate (of an externally controlled ADC) (f_c)

The number of conversions per unit time.

NOTE 1: The maximum conversion rate should be specified for full resolution.

NOTE 2: The conversion rate is usually expressed as the number of conversions per second.

NOTE 3: Due to additionally needed settling or recovery times, the maximum specified conversion rate is smaller than the reciprocal of the worst-case conversion time.

Conversion Time (of an ADC) (t_c)

The time elapsed between the command to perform a conversion and the appearance at the converter output of the complete digital representation of the analog input value.

Delay Time, (Digital) (of a linear or a multiplying DAC) (t_d , t_{dd})

The time interval between the instant when the digital input changes and the instant when the analog output passes a specified value that is close to its initial value, ignoring glitches (see Figure 8).

NOTE: For a multiplying DAC, the full term and the additional subscript d must be used to distinguish between the digital and the delay time.

Delay Time, Reference (of a multiplying DAC) (t_{dr})

The time interval between the instant when a step change of the reference voltage occurs and the instant when the analog output passes a specified value that is close to its initial value.

Feedthrough Capacitance (C_f)

The value of the capacitance for a specified value of R in an equivalent circuit for the calculation of the feedthrough error.

NOTE: The equivalent circuit consists of a high-pass R-C filter between the reference input and the analog output.

Feedthrough Error (see Part 4)

Glitch (of a DAC)

A short, undesirable transient in the analog output occurring following a code change at the digital input (see Figure 8).

Glitch Area (of a DAC)

The time integral of the analog value of the glitch transient.

NOTE 1: Usually, the maximum specified glitch area refers to a specified worst-case code change.

NOTE 2: Instead of a letter symbol, the abbreviation GA is in use.

Glitch Energy (of a DAC)

The time integral of the electrical power of the glitch transient.

NOTE 1: Usually, the maximum specified glitch energy refers to a specified worst-case code change.

NOTE 2: Instead of a letter symbol, the abbreviation GE is in use.

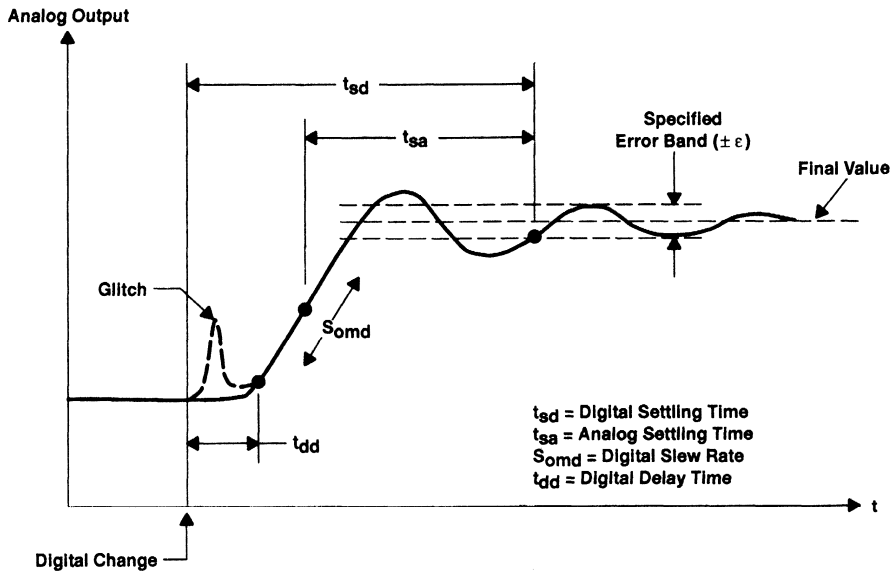


Figure 8. Output Characteristics of a Linear or a Multiplying DAC for a Step Change in the Digital Input Code

Pedestal (Error) (E_p) (see Part 4)

Ramp Delay, Steady-state (of a multiplying DAC) ($t_{d(ramp)}$)

The time separation between the actual curve of the analog output and the theoretical curve (with no delay) for a ramp in reference voltage, after the settling time to steady-state ramp has elapsed (see Figure 9).

Settling Time, Analog (of a DAC) (t_{sa})

The time interval between the instant when the analog output passes a specified value and the instant when the analog output enters for the last time a specified error band about its final value (see Figures 8 and 10).

Settling Time, (Digital) (of a linear or a multiplying DAC) (t_s , t_{sd})

The time interval between the instant when the digital input changes and the instant when the analog output value enters for the last time a specified error band about its final value (see Figure 8).

NOTE: For a multiplying DAC, the full term and the additional subscript d must be used to distinguish between the digital and the settling time.

Settling Time, Reference (of a multiplying DAC) (t_{sr})

The time interval between the instant when a step change of the reference voltage occurs and the instant when the analog output enters for the last time a specified error band about its final value (see Figure 10).

NOTE: Specifications for the reference settling time are usually given for the highest allowed step change in reference voltage.

Settling Time to Steady-State Ramp (of a multiplying DAC) ($t_{s(ramp)}$)

The time interval between the instant a ramp in the reference voltage starts and the instant when the analog output value enters for the last time a specified error band about the final ramp in the output (see Figure 9).

GLOSSARY TERMS, DEFINITIONS AND LETTER SYMBOLS

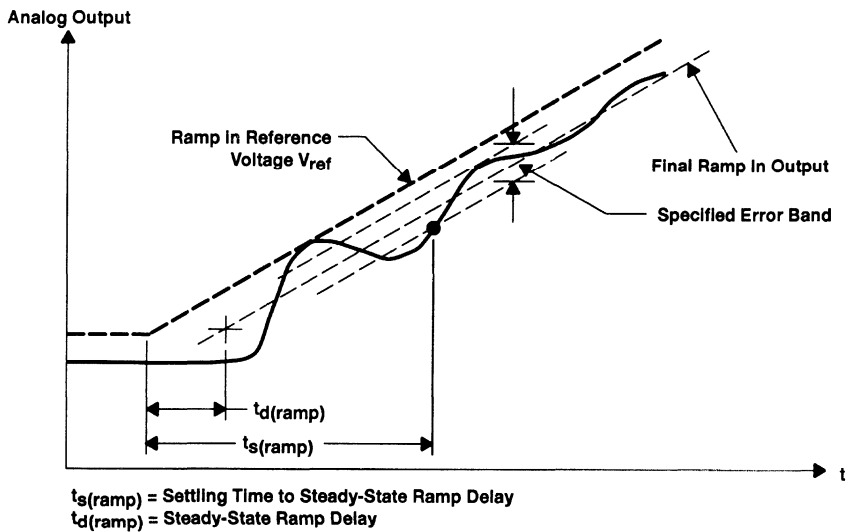


Figure 9. Output Characteristics for a Ramp in Reference Voltage of a Multiplying DAC

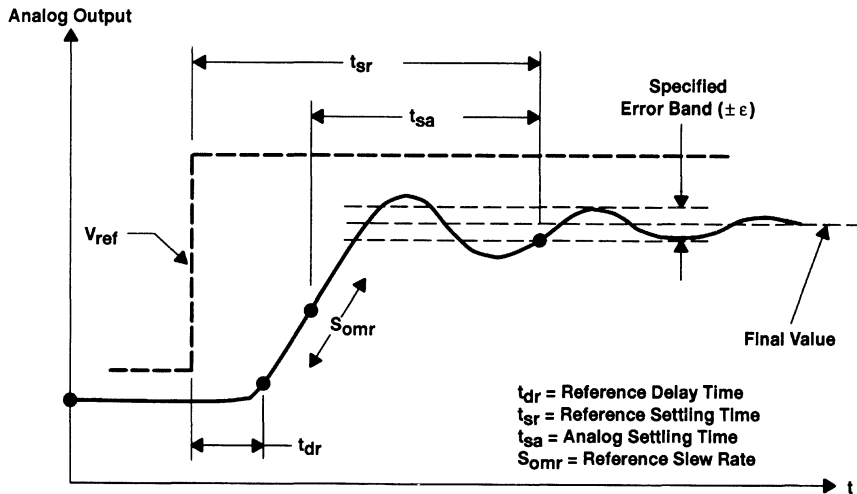


Figure 10. Output Characteristics for a Step Change in Reference Voltage of a Multiplying DAC

Skewing Time, Internal (of a DAC)

The difference in internal delay between the individual output transitions for a given change of digital input.

NOTE: The internal (and external) skew has a major influence on the settling time for critical changes in the digital input, for example, for a 1-LSB change from 011 . . . 111 to 100 . . . 000, and is an important source of commutation noise.

Slew Rate, (Digital) (of a linear or a multiplying DAC) (S_{OM} , S_{OMD})

The maximum rate of change of the analog output value when a change of the digital input code causes a large step change of the analog output value (see Figure 8).

NOTE 1: For a multiplying DAC, the full term and the additional subscript D must be used to distinguish between the digital and the slew rate.

NOTE 2: The abbreviations SR and SR(dig) are also used.

Slew Rate, Reference (of a multiplying DAC) (S_{OMR})

The maximum rate of change of the analog output following a large step change of the reference voltage (see Figure 10).

NOTE: The abbreviation SR(ref) is also used.

4. ERRORS, ACCURACY

The definitions in this section describe the errors as the difference between the actual value and the nominal value of the analog quantity. As such they may be expressed in conventional units (for example, millivolts) or as multiples or submultiples of 1 LSB. An error can also be expressed as a relative value, for example, in % of FSR. In this case, it is common practice to use the same term as for the analog value.

Absolute Accuracy Error

Synonym for total error.

Feedthrough Error (of a multiplying DAC) (E_F)

An error in analog output due to variation in the reference voltage that appears as an offset error and is proportional to frequency and amplitude of the reference signal.

NOTE 1: The specification for the feedthrough error is given for the digital input for which the offset error is specified, and for a reference signal of specified frequency and amplitude.

NOTE 2: This error may also be expressed as a peak-to-peak analog value.

Full-Scale Error (of a linear ADC or DAC) (E_{FS})

The difference between the actual midstep value or step value and the nominal midstep value or step value, respectively, at specified full scale.

NOTE: Normally, this error specification is applied to converters that have no arrangement for an external adjustment of offset error and gain error.

Gain Error (of a linear ADC or DAC) (E_G)

For an ADC: The difference between the actual midstep value and the nominal midstep value in the transfer diagram at the specified gain point after the offset error has been adjusted to zero [see Figure 11(a)].

For a DAC: The difference between the actual step value and the nominal step value in the transfer diagram at the specified gain point after the offset error has been adjusted to zero [see Figure 11(b)].

NOTE: See Notes 1 and 2 under Offset Error.

GLOSSARY TERMS, DEFINITIONS AND LETTER SYMBOLS

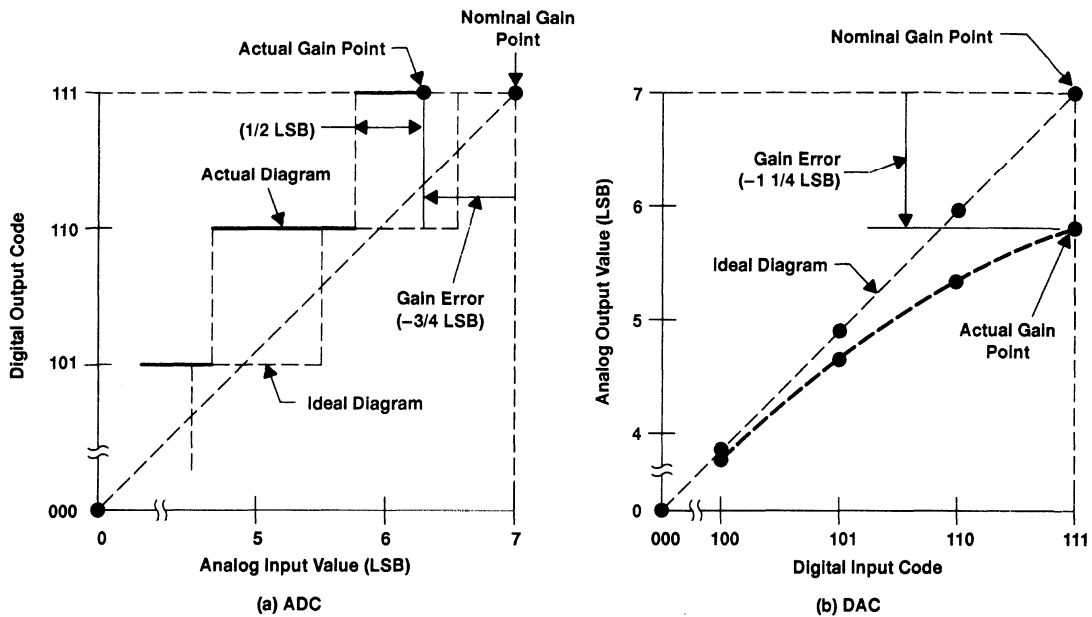


Figure 11. Gain Error of a Linear 3-Bit Natural Binary Code Converter (Specified at Step 111), After Correction of the Offset Error

Instability, Long-Term (Accuracy) ($\Delta E_{(\Delta t)}$, $\Delta E_{(t)}$)

The additional error caused by the aging of the components and specified for a longer period in time.

Linearity Error, Best-Straight-Line (of a linear and adjustable ADC) ($E_{L(ad)}$)

The difference between the actual analog value at the transition between any two adjacent steps and its ideal value after offset error and gain error have been adjusted to minimize the magnitude of the extreme values of this difference [see Figure 12(a)].

NOTE 1: The inherent quantization error is not included in the best-straight-line linearity error of an ADC. The ideal value for the transition corresponds to the nominal midstep value $\pm 1/2$ LSB.

NOTE 2: For a uniformly curved transfer diagram, the extreme values will be very close to half of the magnitude of the end-point linearity error [see Figure 12(a)].

Linearity Error, Best-Straight-Line (of a linear and adjustable DAC) ($E_{L(ad)}$)

The difference between the actual step value and the nominal step value after offset error and gain error have been adjusted to minimize the magnitude of the extreme values of this difference [see Figure 12(b)].

NOTE: For a uniformly curved transfer diagram, the extreme values will be very close to half of the magnitude of the end-point linearity error [see Figure 12(b)].

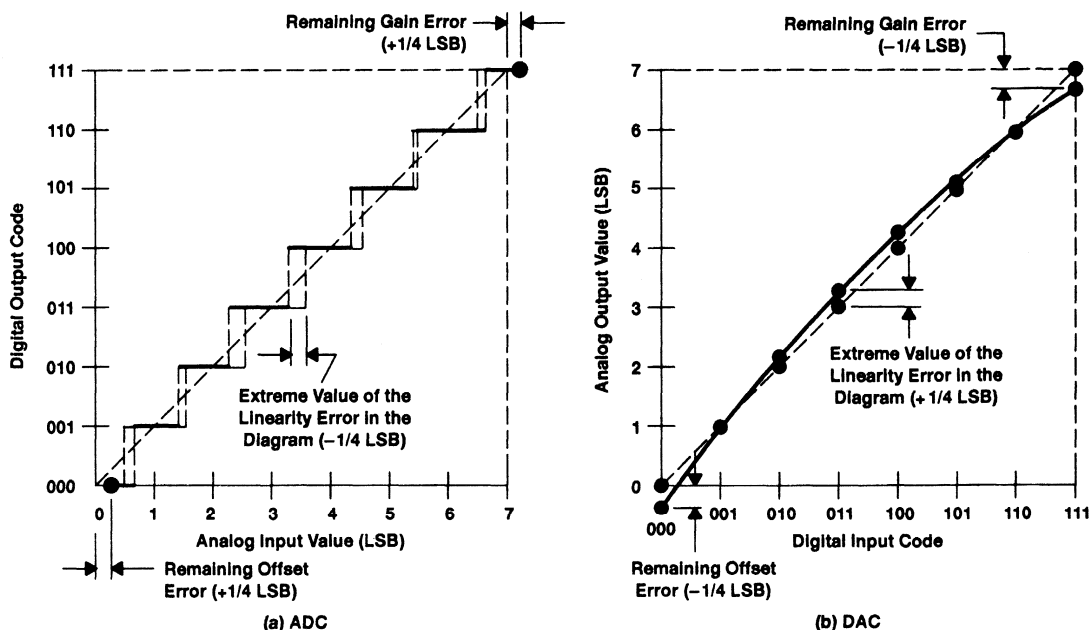


Figure 12. Best-Straight-Line Linearity Error of a Linear 3-Bit Natural Binary-Coded Converter (Values Between $\pm 1/4$ LSB)

Linearity Error, Differential (of a linear ADC or DAC) (E_D)

The difference between the actual step width or step height and the ideal value (1 LSB) (see Figure 13).

NOTE: A differential linearity error greater than 1 LSB can lead to missing codes in an ADC or to nonmonotonicity of an ADC or a DAC (see Figures 6 and 7).

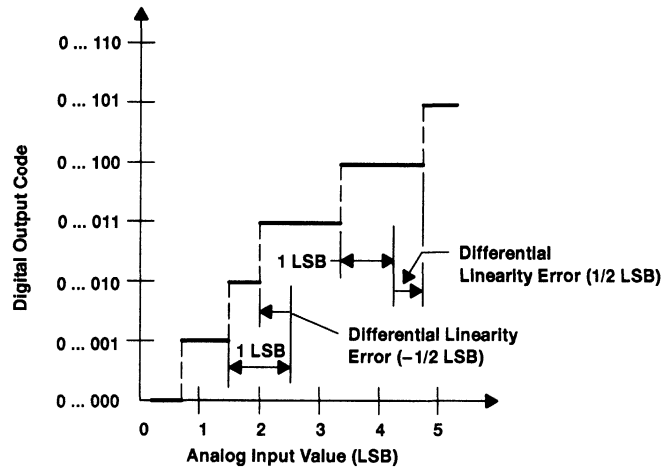
Linearity Error, End-Point (of a linear and adjustable ADC) (E_L)

The difference between the actual analog value at the transition between any two adjacent steps and its ideal value after offset error and gain error have been adjusted to zero [see Figure 14(a)].

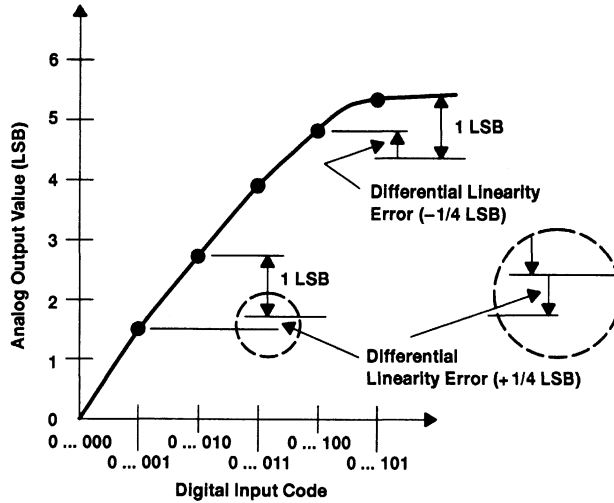
NOTE 1: The short term linearity error is in common use and is sufficient if no ambiguity with the best-straight-line linearity error is likely to occur.

NOTE 2: The inherent quantization error is not included in the linearity error of an ADC. The ideal value for the transition corresponds to the nominal midstep value $\pm 1/2$ LSB.

GLOSSARY TERMS, DEFINITIONS AND LETTER SYMBOLS



(a) ADC



(b) DAC

Figure 13. Differential Linearity Error of a Linear ADC or DAC

Linearity Error, End-Point (of a linear and adjustable DAC) (E_L)

The difference between the actual step value and the nominal step value after offset error and gain error have been adjusted to zero [see Figure 14(b)].

NOTE : The short term linearity error is in common use and is sufficient if no ambiguity with the best-straight-line linearity error is likely to occur.

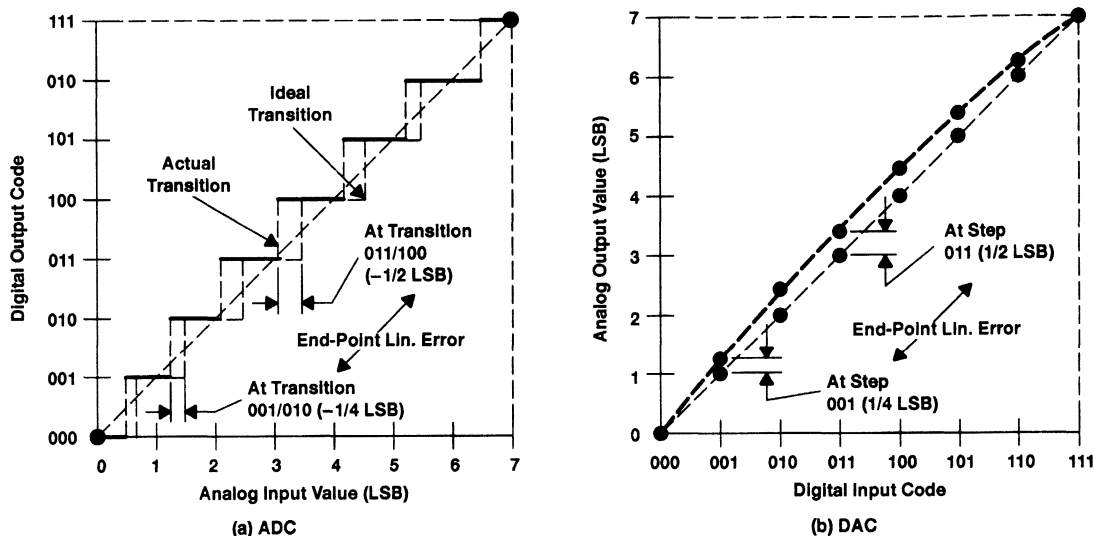


Figure 14. End-Point Linearity Error of a Linear 3-Bit Natural Binary-Coded ADC or DAC (Offset Error and Gain Error are Adjusted to the Value Zero)

Offset Error (of a linear ADC or DAC) (E_O)

For an ADC: The difference between the actual midstep value and the nominal midstep value at the offset point [see Figure 15(a)].

For a DAC: The difference between the actual step value and the nominal step value at the offset point [see Figure 15(b)].

NOTE 1: Usually, the specified steps for the specification of offset error and gain error are the steps at the ends of the practical full-scale range. For an ADC, the midstep value of these steps is defined as the value for a point 1/2 LSB apart from the adjacent transition (see Figures 11 and 15).

NOTE 2: The terms offset error and gain error should be used only for error that can be adjusted to zero. Otherwise, the terms zero-scale error and full-scale error should be used.

Pedestal (Error) (E_p)

A dynamic offset produced in the commutation process.

GLOSSARY

TERMS, DEFINITIONS AND LETTER SYMBOLS

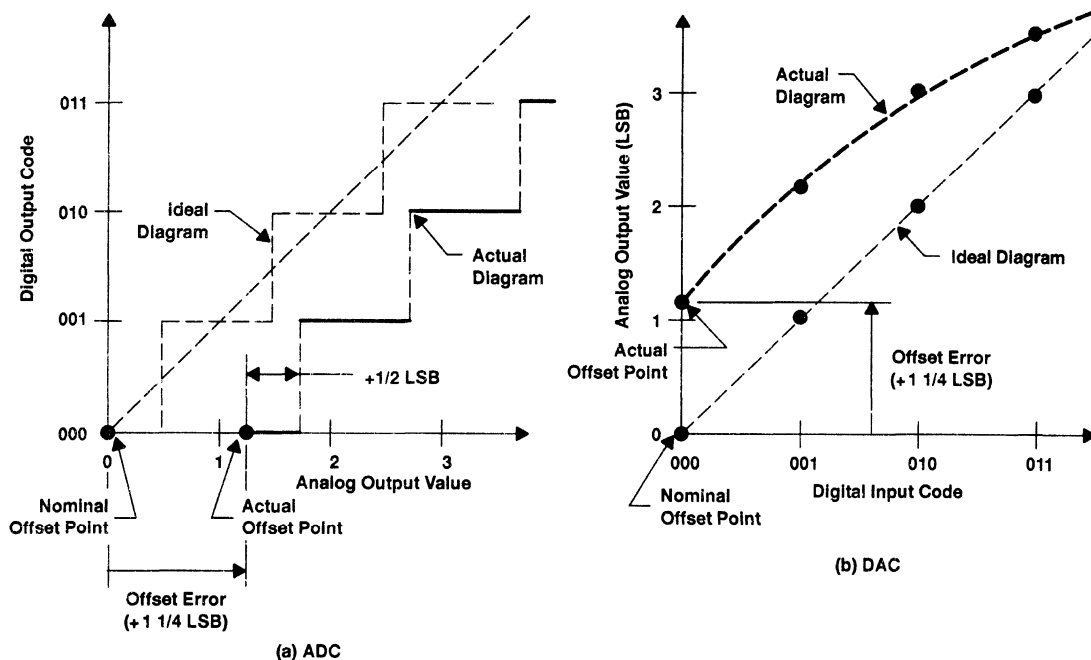


Figure 15. Offset Error of a Linear 3-Bit Natural Binary Code Converter (Specified at Step 000)

Quantization Error, Inherent (of an ideal ADC)

Within a step, the maximum (positive or negative) possible deviation of the actual analog input value from the nominal midstep value.

NOTE 1: This error follows necessarily from the quantization procedure. For a linear ADC, its value equals $\pm 1/2$ LSB (see Figure 1).

NOTE 2: The term resolution error for the inherent quantization error is deprecated, because resolution as a design parameter has only a nominal value.

Rollover Error (of an ADC with decimal output and auto-polarity) (E_{RO})

The difference in output readings with the analog input switched between positive and negative values of the same magnitude (close to full scale).

Total Error (of a linear ADC) (E_T)

The maximum difference (positive or negative) between an analog value and the nominal midstep value within any step [see Figure 16(a)].

NOTE 1: If this error is expressed as a relative value, the term relative accuracy error should be used instead of absolute accuracy error.

NOTE 2: This error includes contributions from offset error, gain error, linearity error, and the inherent quantization error.

Total Error (of a linear DAC) (E_T)

The difference (positive or negative) between the actual step value and the nominal step value for any step [see Figure 16(b)].

NOTE 1: If this error is expressed as a relative value, the term relative accuracy error should be used instead of absolute accuracy error.

NOTE 2: This error includes contributions from offset error, gain error, and linearity error.

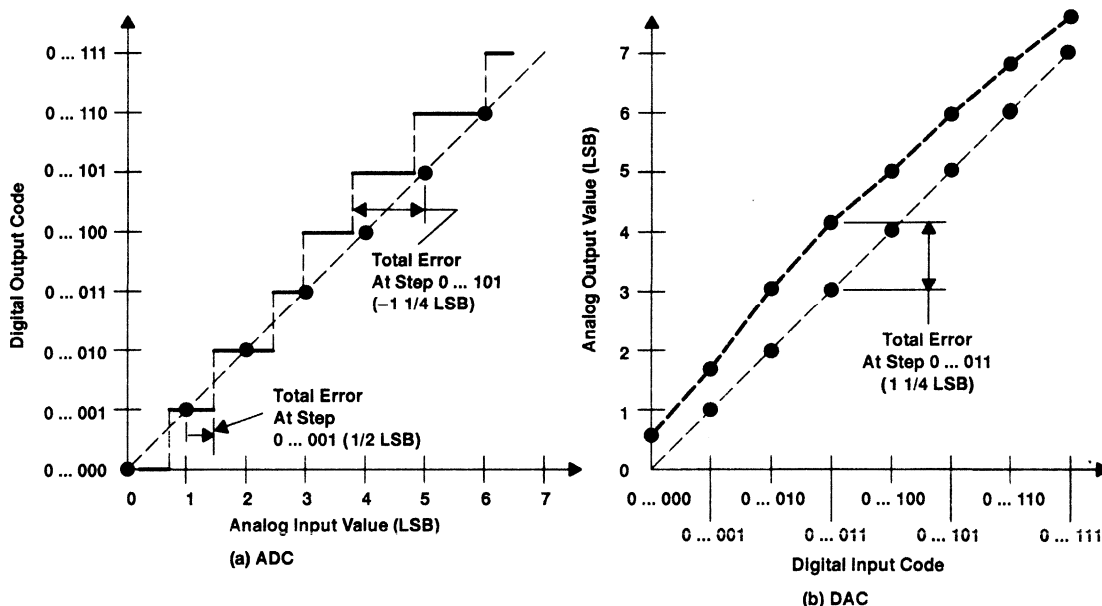


Figure 16. Absolute Accuracy Error, Total Error of a Linear ADC or DAC

Zero-Scale Error (of a linear ADC or DAC) (E_{zs})

The difference between the actual midstep value or step value and the nominal midstep value or step value, respectively, at specified zero scale.

NOTE: Normally, this error specification is applied to converters that have no arrangement for an external adjustment of offset error and gain error.

5. Dynamic and Sigma-Delta Definitions

Resolution

The number of different output codes possible. Expressed as N, where 2^N is the number of available output codes.

Dynamic Range

The ratio of the largest allowable input signal to the noise floor.

Total Harmonic Distortion

The ratio of the rms sum of all harmonics to the rms value of the largest allowable input signal. Units in dB's.

GLOSSARY

TERMS, DEFINITIONS AND LETTER SYMBOLS

Signal to Intermodulation Distortion

The ratio of the rms sum of two input signals to the rms sum of all discernible intermodulation and harmonic distortion products.

Linearity Error

The deviation of a code from a straight line passing through the endpoints of the transfer function after zero- and full-scale errors have been accounted for. Zero-scale is a point 1/2 LSB below the first code transition and full-scale is a point 1/2 LSB beyond the code transition to all ones. The deviation is measured from the middle of each particular code. Units in %FS.

Differential Nonlinearity

The deviation of a code's width from the ideal width in LSB's.

Positive Full Scale Error

The deviation of the last code transition from the ideal, ($V_{ref} - 1.5 \text{ LSB}$).

Positive Full Scale Drift

The drift in effective, positive, full-scale input voltage with temperature.

Negative Full Scale Error

The deviation of the first code transition from the ideal, ($-V_{ref} + 0.5 \text{ LSB}$).

Negative Full Scale Drift

The drift in effective, negative, full-scale input voltage with temperature.

Bipolar Offset

The deviation of the midscale transition from the ideal. The ideal is defined as the middle transition lying on a straight line between actual positive full-scale and actual negative full-scale.

Bipolar Offset Drift

The drift in the bipolar offset error with temperature.

Absolute Group Delay

The delay through the filter section of the part.

Passband Frequency

The upper -3 dB frequency.

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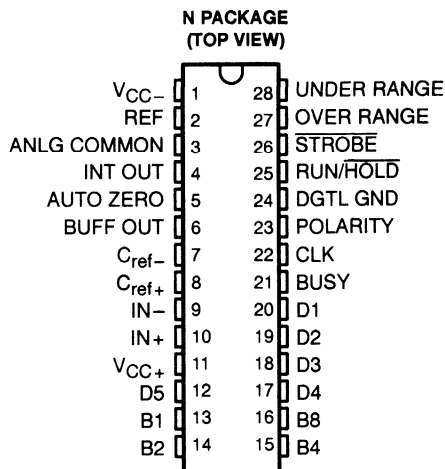
2

General Purpose ADCs

ICL7135C, TLC7135C 4 1/2-DIGIT PRECISION ANALOG-TO-DIGITAL CONVERTERS

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- Zero Reading for 0-V Input
- Precision Null Detection With True Polarity at Zero
- 1-pA Typical Input Current
- True Differential Input
- Multiplexed Binary-Coded-Decimal (BCD) Output
- Low Rollover Error: ± 1 Count Max
- Control Signals Allow Interfacing With UARTs or Microprocessors
- Autoranging Capability With Over- and Under-Range Signals
- TTL-Compatible Outputs
- Direct Replacement for Teledyne TSC7135, Intersil ICL7135, Maxim ICL7135, and Sillconix SI7135
- CMOS Technology



description

The ICL7135C and TLC7135C converters are manufactured with Texas Instruments highly efficient CMOS technology. This 4 1/2-digit, dual-slope-integrating, analog-to-digital converter (DAC) is designed to provide interfaces to both a microprocessor and a visual display. The digit-drive outputs D1 through D4 and multiplexed binary-coded-decimal outputs B1, B2, B4, and B8 provide an interface for LED or LCD decoder/drivers as well as microprocessors.

The ICL7135C and TLC7135C offer 50-ppm (one part in 20,000) resolution with a maximum linearity error of one count. The zero error is less than 10 μ V and zero drift is less than 0.5 μ V/ $^{\circ}$ C. Source-impedance errors are minimized by low input current (less than 10 pA). Rollover error is limited to ± 1 count.

The BUSY, STROBE, RUN/HOLD, OVER RANGE, and UNDER RANGE control signals support microprocessor-based measurement systems. The control signals also can support remote data acquisition systems with data transfer through universal asynchronous receiver transmitters (UARTs).

The ICL7135C and TLC7135C are characterized for operation from 0 $^{\circ}$ C to 70 $^{\circ}$ C.

AVAILABLE OPTIONS

T _A	PACKAGE
	PLASTIC DIP (N)
0 $^{\circ}$ C to 70 $^{\circ}$ C	ICL7135CN
	TLC7135CN



Caution. These devices have limited built-in protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

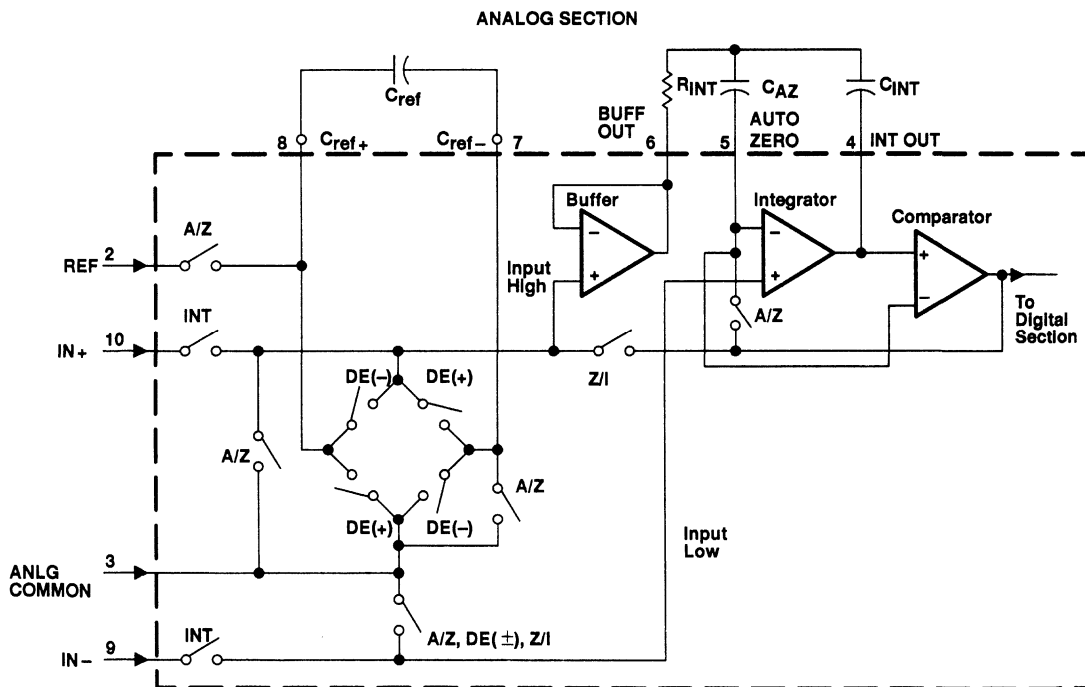
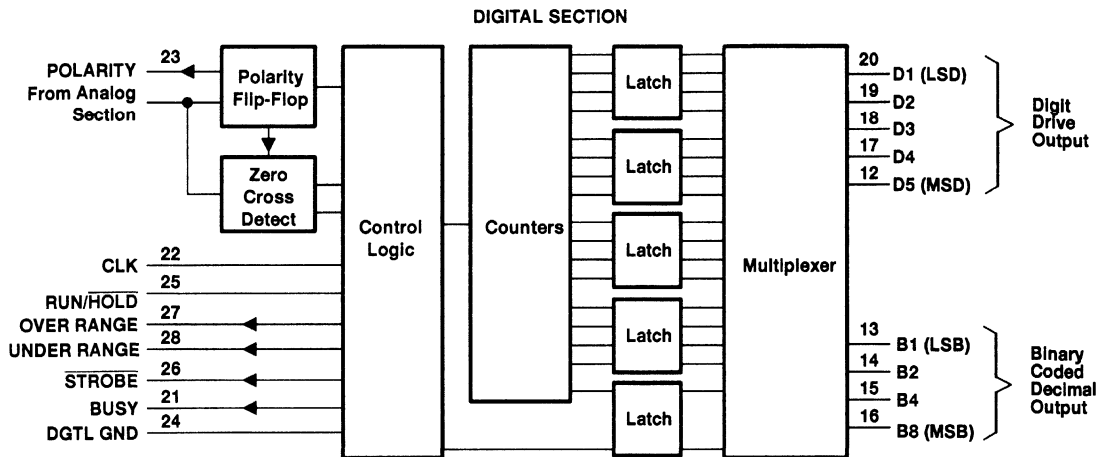
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functional block diagram



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage (V_{CC+} with respect to V_{CC-})	15 V
Analog input voltage ($IN-$ or $IN+$)	V_{CC-} to V_{CC+}
Reference voltage range	V_{CC-} to V_{CC+}
Clock input voltage range	0 V to V_{CC+}
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+}	4	5	6	V
Supply voltage, V_{CC-}	-3	-5	-8	V
Reference voltage, V_{ref}		1		V
High-level input voltage, CLK, RUN/HOLD, V_{IH}	2.8			V
Low-level input voltage, CLK, RUN/HOLD, V_{IL}			0.8	V
Differential input voltage, V_{ID}	$V_{CC-} + 1$		$V_{CC+} - 0.5$	V
Maximum operating frequency, f_{clock} (see Note 1)	1.2	2		MHz
Operating free-air temperature range, T_A	0		70	°C

NOTE 1: Clock frequency range extends down to 0 Hz.

electrical characteristics, $V_{CC+} = 5 V$, $V_{CC-} = 5 V$, $V_{ref} = 1 V$, $f_{clock} = 120 kHz$, $T_A = 25°C$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	D1-D5, B1, B2, B4, B8	$I_O = -1 mA$	2.4	5	V
		Other outputs	$I_O = -10 \mu A$	4.9	5	
V_{OL}	Low-level output voltage		$I_O = 1.6 mA$		0.4	V
$V_{ON(PP)}$	Peak-to-peak output noise voltage (see Note 2)	$V_{ID} = 0$, Full scale = 2 V		15		μV
α_{VO}	Zero-reading temperature coefficient of output voltage	$V_{ID} = 0$, 0°C ≤ T_A ≤ 70°C		0.5	2	$\mu V/°C$
I_{IH}	High-level input current	$V_I = 5 V$, 0°C ≤ T_A ≤ 70°C		0.1	10	μA
I_{IL}	Low-level input current	$V_I = 0 V$, 0°C ≤ T_A ≤ 70°C		-0.02	-0.1	mA
I_I	Input leakage current, $IN-$ and $IN+$	$V_{ID} = 0$	$T_A = 25°C$	1	10	pA
			0°C ≤ T_A ≤ 70°C		250	
I_{CC+}	Positive supply current	$f_{clock} = 0$	$T_A = 25°C$	1	2	mA
			0°C ≤ T_A ≤ 70°C		3	
I_{CC-}	Negative supply current	$f_{clock} = 0$	$T_A = 25°C$	-0.8	-2	mA
			0°C ≤ T_A ≤ 70°C		-3	
C_{pd}	Power dissipation capacitance	See Note 3		40		pF

NOTES: 2. This is the peak-to-peak value that is not exceeded 95% of the time.

3. Factor-relating clock frequency to increase in supply current. At $V_{CC+} = 5 V$, $I_{CC+} = I_{CC+}(f_{clock} = 0) + C_{pd} \times 5 V \times f_{clock}$

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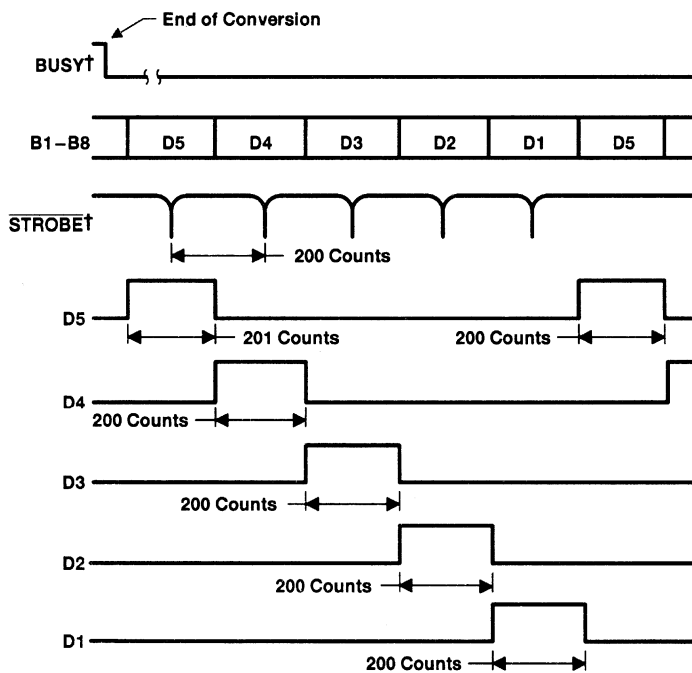
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operating characteristics, $V_{CC+} = 5\text{ V}$, $V_{CC-} = 5\text{ V}$, $V_{ref} = 1\text{ V}$, $f_{clock} = 120\text{ kHz}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
α_{FS} Full-scale temperature coefficient (see Note 4)	$V_{ID} = 2\text{ V}$, $0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$			5	ppm/ $^\circ\text{C}$
E_L Linearity error	$-2\text{ V} \leq V_{ID} \leq 2\text{ V}$		0.5		count
E_D Differential linearity error (see Note 5)	$-2\text{ V} \leq V_{ID} \leq 2\text{ V}$		0.01		LSB
E_{FS} \pm Full-scale symmetry error (rollover error) (see Note 6)	$V_{ID} = \pm 2\text{ V}$		0.5	1	count
Display reading with 0-V input	$V_{ID} = 0$, $0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$	-0.0000	± 0.0000	0.0000	Digital Reading
Display reading in ratiometric operation	$V_{ID} = V_{ref}$, $T_A = 25^\circ\text{C}$	0.9998	0.9999	1.0000	Digital Reading
	$0^\circ\text{C} \leq T_A \leq 70^\circ\text{C}$	0.9995	0.9999	1.0005	

- NOTES: 4. This parameter is measured with an external reference having a temperature coefficient of less than 0.01 ppm/ $^\circ\text{C}$.
 5. The magnitude of the difference between the worst case step of adjacent counts and the ideal step.
 6. Rollover error is the difference between the absolute values of the conversion for 2 V and -2 V.

timing diagrams



† Delay between BUSY going low and the first $\overline{\text{STROBE}}$ pulse is dependent upon the analog input.

Figure 1

timing diagrams (continued)

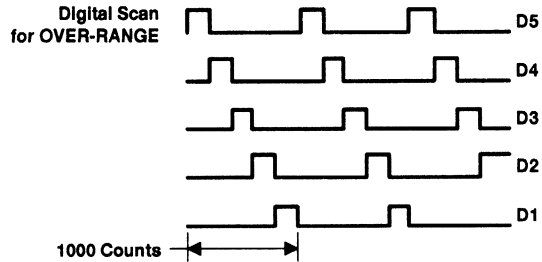


Figure 2

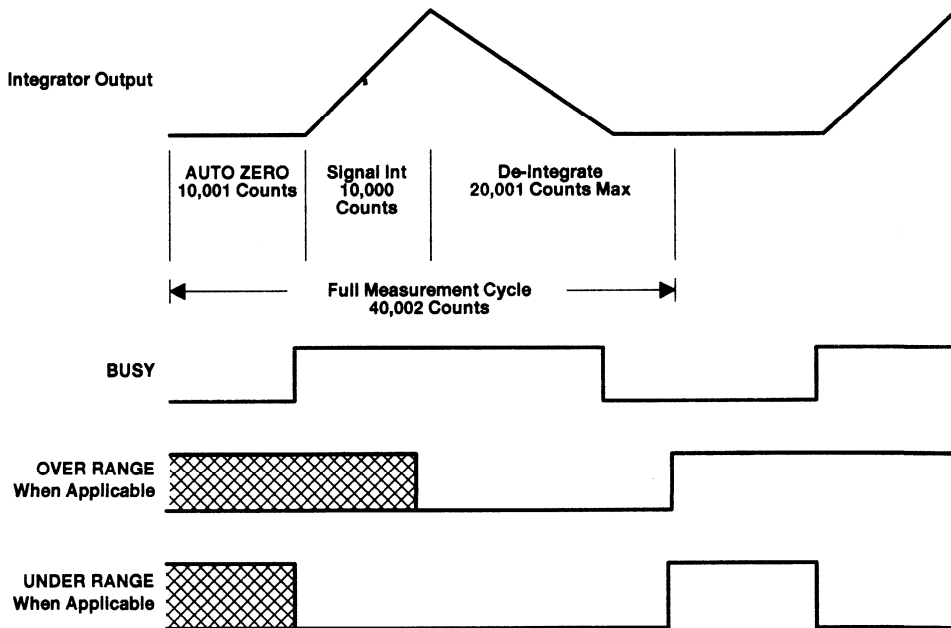
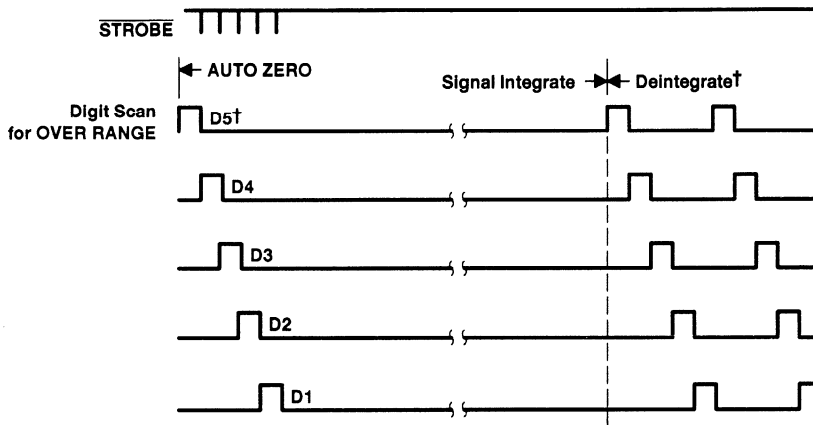


Figure 3

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timing diagrams (continued)



† First D5 of AUTO ZERO and deintegrate is one count longer.

Figure 4

PRINCIPLES OF OPERATION

A measurement cycle for the ICL7135C and TLC7135C consists of the following four phases.

1. Auto-Zero Phase. The internal IN+ and IN- inputs are disconnected from the terminals and internally connected to ANLG COMMON. The reference capacitor is charged to the reference voltage. The system is configured in a closed loop and the auto-zero capacitor is charged to compensate for offset voltages in the buffer amplifier, integrator, and comparator. The auto-zero accuracy is limited only by the system noise, and the overall offset, as referred to the input, is less than 10 μ V.
2. Signal Integrate Phase. The auto-zero loop is opened and the internal IN+ and IN- inputs are connected to the external terminals. The differential voltage between these inputs is integrated for a fixed period of time. When the input signal has no return with respect to the converter power supply, IN- can be tied to ANLG COMMON to establish the correct common-mode voltage. Upon completion of this phase, the polarity of the input signal is recorded.
3. deintegrate Phase. The reference is used to perform the deintegrate task. The internal IN- is internally connected to ANLG COMMON and IN+ is connected across the previously charged reference capacitor. The recorded polarity of the input signal ensures that the capacitor is connected with the correct polarity so that the integrator output polarity returns to zero. The time required for the output to return to zero is proportional to the amplitude of the input signal. The return time is displayed as a digital reading and is determined by the equation $10,000 \times (V_{ID}/V_{ref})$. The maximum or full-scale conversion occurs when V_{ID} is two times V_{ref} .
4. Zero Integrator Phase. The internal IN- is connected to ANLG COMMON. The system is configured in a closed loop to cause the integrator output to return to zero. Typically, this phase requires 100 to 200 clock pulses. However, after an over-range conversion, 6200 pulses are required.

PRINCIPLES OF OPERATION

description of analog circuits

Input signal range

The common mode range of the input amplifier extends from 1 V above the negative supply to 1 V below the positive supply. Within this range, the common-mode rejection ratio (CMRR) is typically 86 dB. Both differential and common-mode voltages cause the integrator output to swing. Therefore, care must be exercised to ensure that the integrator output does not become saturated.

analog common

Analog common (ANLG COMMON) is connected to the internal IN– during the auto-zero, deintegrate, and zero integrator phases. When IN– is connected to a voltage that is different than analog common during the signal integrate phase, the resulting common-mode voltage is rejected by the amplifier. However, in most applications, IN– is set at a known fixed voltage (i.e., power supply common for instance). In this application, analog common should be tied to the same point, thus removing the common-mode voltage from the converter. Removing the common-mode voltage in this manner slightly increases conversion accuracy.

reference

The reference voltage is positive with respect to analog common. The accuracy of the conversion result is dependent upon the quality of the reference. Therefore, to obtain a high accuracy conversion, a high quality reference should be used.

description of digital circuits

RUN/HOLD input

When RUN/HOLD is high or open, the device continuously performs measurement cycles every 40.002 clock pulses. When this input is taken low, the integrated circuit continues to perform the ongoing measurement cycle and then hold the conversion reading for as long as the terminal is held low. When the terminal is held low after completion of a measurement cycle, a short positive pulse (greater than 300 ns) initiates a new measurement cycle. When this positive pulse occurs before the completion of a measurement cycle, it will not be recognized. The first STROBE pulse, which occurs 101 counts after the end of a measurement cycle, is an indication of the completion of a measurement cycle. Thus, the positive pulse could be used to trigger the start of a new measurement after the first STROBE pulse.

STROBE input

Negative going pulses from this input transfer the BCD conversion data to external latches, UARTs, or microprocessors. At the end of the measurement cycle, STROBE goes high and remains high for 201 counts. The most significant digit (MSD) BCD bits are placed on the BCD terminals. After the first 101 counts, halfway through the duration of output D1–D5 going high, the STROBE terminal goes low for 1/2 clock pulse width. The placement of the STROBE pulse at the midpoint of the D5 high pulse allows the information to be latched into an external device on either a low-level or an edge. Such placement of the STROBE pulse also ensures that the BCD bits for the second MSD are not yet competing for the BCD lines and latching of the correct bits is ensured. The above process is repeated for the second MSD and the D4 output. Similarly, the process is repeated through the least significant digit (LSD). Subsequently, inputs D5 through D1 and the BCD lines continue scanning without the inclusion of STROBE pulses. This subsequent continuous scanning causes the conversion results to be continuously displayed. Such subsequent scanning does not occur when an over-range condition occurs.

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PRINCIPLES OF OPERATION

BUSY output

The BUSY output goes high at the beginning of the signal integrate phase. BUSY remains high until the first clock pulse after zero crossing or at the end of the measurement cycle when an over-range condition occurs. It is possible to use the BUSY terminal to serially transmit the conversion result. Serial transmission can be accomplished by ANDing the BUSY and CLOCK signals and transmitting the ANDed output. The transmitted output consists of 10,001 clock pulses, which occur during the signal integrate phase, and the number of clock pulses that occur during the deintegrate phase. The conversion result can be obtained by subtracting 10,001 from the total number of clock pulses.

OVER-RANGE output

When an over-range condition occurs, this terminal goes high after the BUSY signal goes low at the end of the measurement cycle. As previously noted, the BUSY signal remains high until the end of the measurement cycle when an over-range condition occurs. The OVER RANGE output goes high at the end of BUSY and goes low at the beginning of the deintegrate phase in the next measurement cycle.

UNDER-RANGE output

At the end of the BUSY signal, this terminal goes high when the conversion result is less than or equal to 9% (count of 1800) of the full-scale range. The UNDER RANGE output is brought low at the beginning of the signal integrate phase of the next measurement cycle.

POLARITY output

The POLARITY output is high for a positive input signal and updates at the beginning of each deintegrate phase. The polarity output is valid for all inputs including ± 0 and OVER RANGE signals.

digit-drive (D1, D2, D4 and D5) outputs

Each digit-drive output (D1 through D5) sequentially goes high for 200 clock pulses. This sequential process is continuous unless an over-range occurs. When an over-range occurs, all of the digit-drive outputs are blanked from the end of the strobe sequence until the beginning of the deintegrate phase (when the sequential digit-drive activation begins again). The blanking activity during an over-range condition can cause the display to flash and indicate the over-range condition.

BCD outputs

The BCD bits (B1, B2, B4 and B8) for a given digit are sequentially activated on these outputs. Simultaneously, the appropriate digit-drive line for the given digit is activated.

system aspects

integrating resistor

The value of the integrating resistor (R_{INT}) is determined by the full-scale input voltage and the output current of the integrating amplifier. The integrating amplifier can supply 20 μA of current with negligible nonlinearity. The equation for determining the value of this resistor is:

$$R_{INT} = \frac{\text{Full Scale Voltage}}{I_{INT}}$$

Integrating amplifier current, I_{INT} , from 5 to 40 μA yields good results. However, the nominal and recommended current is 20 μA .

PRINCIPLES OF OPERATION

Integrating capacitor

The product of the integrating resistor and capacitor should be selected to give the maximum voltage swing without causing the integrating amplifier output to saturate and get too close to the power supply voltages. When the amplifier output is within 0.3 V of either supply, saturation occurs. With ± 5 -V supplies and ANLG COMMON connected to ground, the designer should design for a ± 3.5 -V to ± 4 -V integrating amplifier swing. A nominal capacitor value is 0.47 μ F. The equation for determining the value of the integrating capacitor (C_{INT}) is:

$$C_{INT} = \frac{10,000 \times \text{Clock Period} \times I_{INT}}{\text{Integrator Output Voltage Swing}}$$

Where:

I_{INT} is nominally 20 μ A.

Capacitors with large tolerances and high dielectric absorption can induce conversion inaccuracies. A capacitor that is too small could cause the integrating amplifier to saturate. High dielectric absorption causes the effective capacitor value to be different during the signal integrate and deintegrate phases. Polypropylene capacitors have very low dielectric absorption. Polystyrene and polycarbonate capacitors have higher dielectric absorption, but also work well.

auto-zero and reference capacitor

Large capacitors tend to reduce noise in the system. Dielectric absorption is unimportant except during power up or overload recovery. Typical values are 1 μ F.

reference voltage

For high-accuracy absolute measurements, a high quality reference should be used.

rollover resistor and diode

The ICL7135C and TLC7135C have a small rollover error; however, it can be corrected. The correction is to connect the cathode of any silicon diode to INT OUT and the anode to a resistor. The other end of the resistor is connected to ANLG COMMON or ground. For the recommended operating conditions, the resistor value is 100 k Ω . This value may be changed to correct any rollover error that has not been corrected. In many noncritical applications the resistor and diode are not needed.

maximum clock frequency

For most dual-slope A/D converters, the maximum conversion rate is limited by the frequency response of the comparator. In this circuit, the comparator follows the integrator ramp with a 3- μ s delay. Therefore, with a 160-kHz clock frequency (6- μ s period), half of the first reference integrate clock period is lost in delay. Hence, the meter reading changes from 0 to 1 with a 50- μ V input, 1 to 2 with a 150- μ V input, 2 to 3 with a 250- μ V input, etc. This transition at midpoint is desirable; however, when the clock frequency is increased appreciably above 160 kHz, the instrument flashes 1 on noise peaks even when the input is shorted. The above transition points assume a 2-V input range is equivalent to 20,000 clock cycles.

When the input signal is always of one polarity, comparator delay need not be a limitation. Clock rates of 1 MHz are possible since nonlinearity and noise do not increase substantially with frequency. For a fixed clock frequency, the extra count or counts caused by comparator delay are a constant and can be subtracted out digitally.

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PRINCIPLES OF OPERATION

maximum clock frequency (continued)

For signals with both polarities, the clock frequency can be extended above 160 kHz without error by using a low value resistor in series with the integrating capacitor. This resistor causes the integrator to jump slightly towards the zero-crossing level at the beginning of the deintegrate phase, and thus compensates for the comparator delay. This series resistor should be 10 Ω to 50 Ω . This approach allows clock frequencies up to 480 kHz.

minimum clock frequency

The minimum clock frequency limitations result from capacitor leakage from the auto-zero and reference capacitors. Measurement cycles as high as 10 μ s are not influenced by leakage error.

rejection of 50-Hz or 60-Hz pickup

To maximize the rejection of 50-Hz or 60-Hz pickup, the clock frequency should be chosen so that an integral multiple of 50-Hz or 60-Hz periods occur during the signal integrate phase. To achieve rejection of these signals, some clock frequencies that can be used are:

50 Hz: 250, 166.66, 125, 100 kHz, etc.

60 Hz: 300, 200, 150, 120, 100, 40, 33.33 kHz, etc.

zero-crossing flip-flop

This flip-flop interrogates the comparator's zero-crossing status. The interrogation is performed after the previous clock cycle and the positive half of the ongoing clock cycle has occurred, so any comparator transients that result from the clock pulses do not affect the detection of a zero-crossing. This procedure delays the zero-crossing detection by one clock cycle. To eliminate the inaccuracy, which is caused by this delay, the counter is disabled for one clock cycle at the beginning of the deintegrate phase. Therefore, when the zero-crossing is detected one clock cycle later than the zero-crossing actually occurs, the correct number of counts is displayed.

noise

The peak-to-peak noise around zero is approximately 15 μ V (peak-to-peak value not exceeded 95% of the time). Near full scale, this value increases to approximately 30 μ V. Much of the noise originates in the auto-zero loop, and is proportional to the ratio of the input signal to the reference.

analog and digital grounds

For high-accuracy applications, ground loops must be avoided. Return currents from digital circuits must not be sent to the analog ground line.

power supplies

The ICL7135C and TLC7135C are designed to work with \pm 5-V power supplies. However, 5-V operation is possible when the input signal does not vary more than \pm 1.5 V from midsupply.

TLC540I, TLC541I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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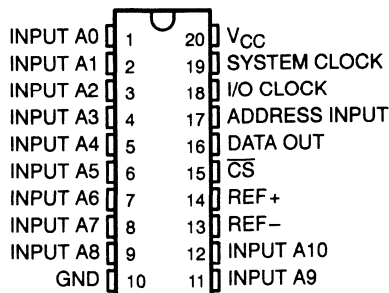
- 8-Bit Resolution A/D Converter
- Microprocessor Peripheral or Stand-Alone Operation
- On-Chip 12-Channel Analog Multiplexer
- Built-in Self-Test Mode
- Software-Controllable Sample and Hold
- Total Unadjusted Error . . . ± 0.5 LSB Max
- TLC541 is Direct Replacement for Motorola MC145040 and National Semiconductor ADC0811. TLC540 is Capable of Higher Speed
- Pinout and Control Signals Compatible with TLC1540 Family of 10-Bit A/D Converters
- CMOS Technology

PARAMETER	TLC540	TLC541
Channel Acquisition Sample Time	2 μ s	3.6 μ s
Conversion Time (Max)	9 μ s	17 μ s
Samples per Second (Max)	75 x 10 ³	40 x 10 ³
Power Dissipation (Max)	12.5 mW	12.5 mW

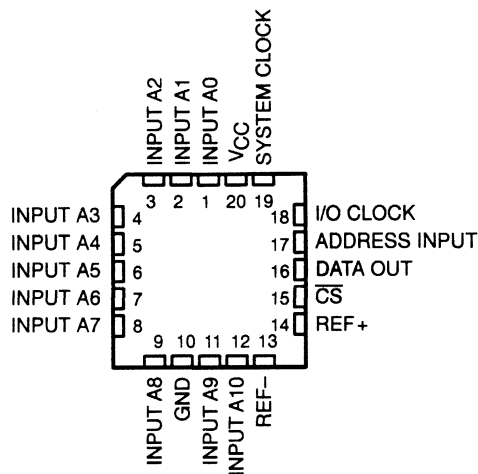
description

The TLC540 and TLC541 are CMOS A/D converters built around an 8-bit switched-capacitor successive-approximation A/D converters. They are designed for serial interface to a microprocessor or peripheral via a 3-state output with up to four control inputs, including independent SYSTEM CLOCK, I/O CLOCK, chip select (\overline{CS}), and ADDRESS INPUT. A 4-MHz system clock for the TLC540 and a 2.1-MHz system clock for the TLC541 with a design that includes simultaneous read/write operation allow high-speed data transfers and sample rates of up to 75,180 samples per second for the TLC540 and 40,000 samples per second for the TLC541. In addition to the high-speed converter and versatile control logic, there is an on-chip 12-channel analog multiplexer that can be used to sample any one of 11 inputs or an internal self-test voltage, and a sample-and-hold that can operate automatically or under microprocessor control. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE		
	SO PLASTIC DIP (DW)	PLASTIC DIP (N)	CHIP CARRIER (FN)
-40°C to 85°C	TLC540IDW TLC541IDW	TLC540IN TLC541IN	TLC540IFN TLC541IFN

TLC540I, TLC541I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

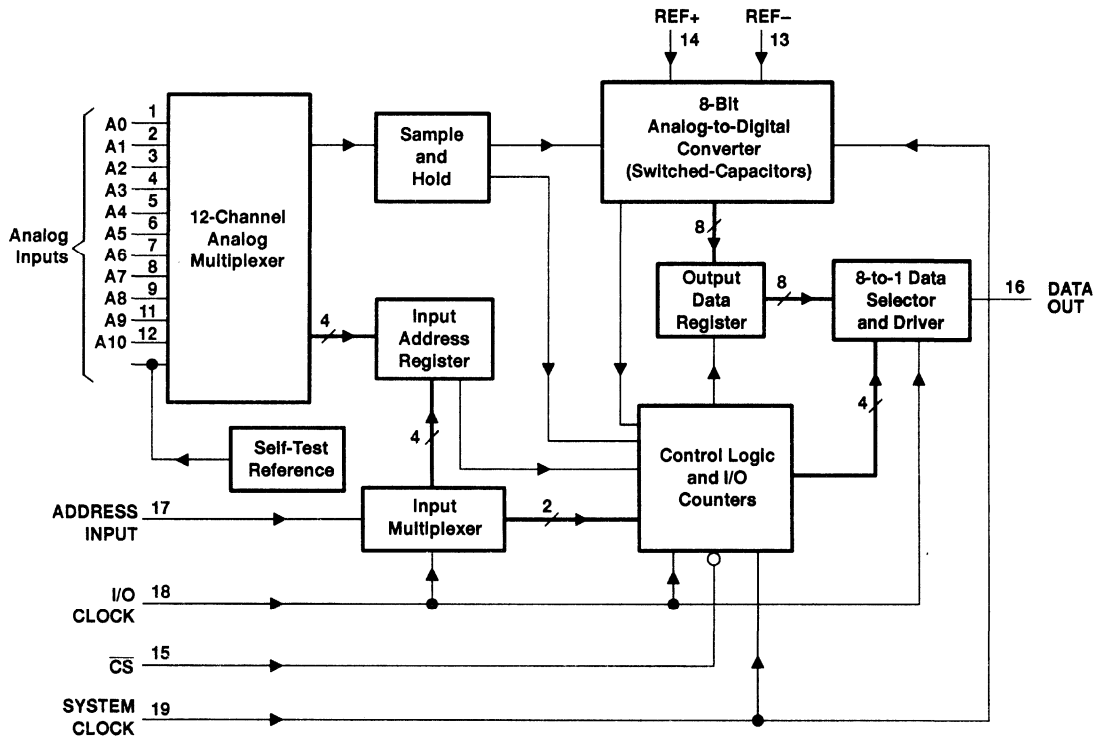
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description (continued)

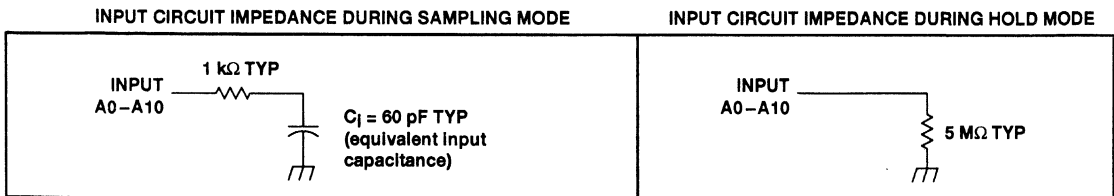
The converters incorporated in the TLC540 and TLC541 feature differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and analog circuitry isolation from logic and supply noises. A switched-capacitor design allows low-error (± 0.5 LSB) conversion in $9 \mu\text{s}$ for the TLC540 and $17 \mu\text{s}$ for the TLC541 over the full operating temperature range.

The TLC540I and TLC541I are characterized for operation from -40°C to 85°C .

functional block diagram



typical equivalent inputs

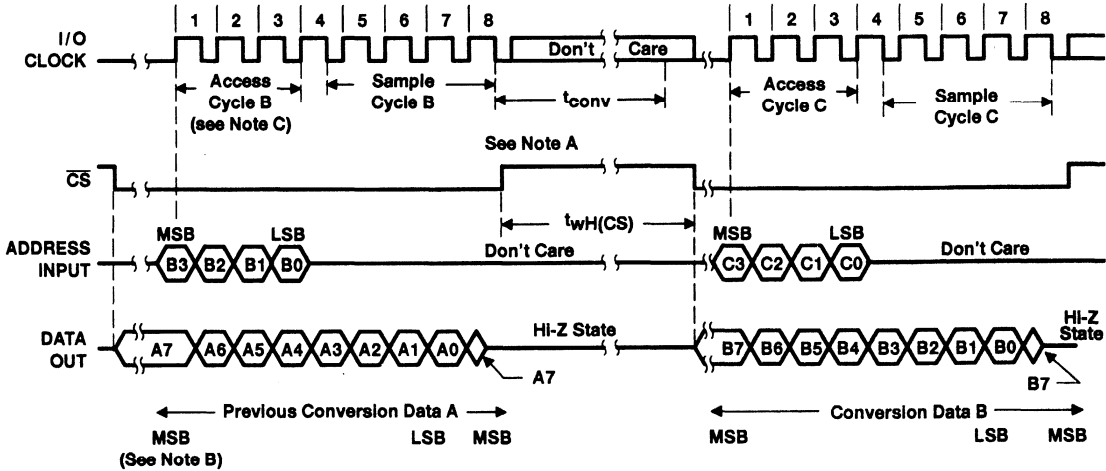


TLC5401, TLC5411

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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operating sequence



- NOTES: A. The conversion cycle, which requires 36 system clock periods, is initiated on the 8th falling edge of I/O CLOCK after \overline{CS} goes low for the channel whose address exists in memory at that time. If \overline{CS} is kept low during conversion, I/O CLOCK must remain low for at least 36 system clock cycles to allow conversion to be completed.
- B. The most significant bit (MSB) will automatically be placed on the DATA OUT bus after \overline{CS} is brought low. The remaining seven bits (A6-A0) will be clocked out on the first seven I/O CLOCK falling edges.
- C. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for three system clock cycles (or less) after a chip select falling edge is detected before responding to control input signals. Therefore, no attempt should be made to clock-in address data until the minimum chip-select setup time has elapsed.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	6.5 V
Input voltage range, V_I (any input)	-0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O	-0.3 V to $V_{CC} + 0.3$ V
Peak input current range (any input)	± 10 mA
Peak total input current (all inputs)	± 30 mA
Operating free-air temperature range, T_A : TLC5401, TLC5411	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds: FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to digital ground with REF- and GND wired together (unless otherwise noted).

TLC540I, TLC541I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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recommended operating conditions

	TLC540			TLC541			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.75	5	5.5	4.75	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)	2.5	V_{CC}	$V_{CC}+0.1$	2.5	V_{CC}	$V_{CC}+0.1$	V
Negative reference voltage, V_{ref-} (see Note 2)	-0.1	0	2.5	-0.1	0	2.5	V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)	1	V_{CC}	$V_{CC}+0.2$	1	V_{CC}	$V_{CC}+0.2$	V
Analog input voltage (see Note 2)	0		V_{CC}	0		V_{CC}	V
High-level control input voltage, V_{IH}	2			2			V
Low-level control input voltage, V_{IL}			0.8			0.8	V
Setup time, address bits at data input before I/O CLOCK \uparrow , $t_{su}(A)$	200			400			ns
Hold time, address bits after I/O CLOCK \uparrow , $t_h(A)$	0			0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su}(CS)$ (see Note 3)	3			3			System clock cycles
\overline{CS} high during conversion, $t_{wH}(CS)$	36			36			System clock cycles
I/O CLOCK frequency, $f_{clock(I/O)}$	0		2.048	0		1.1	MHz
Pulse duration, SYSTEM CLOCK frequency, $f_{clock(SYS)}$	$f_{clock(I/O)}$		4	$f_{clock(I/O)}$		2.1	MHz
Pulse duration, SYSTEM CLOCK high, $t_{wH}(SYS)$	110			210			MHz
Pulse duration, SYSTEM CLOCK low, $t_{wL}(SYS)$	100			190			MHz
Pulse duration, I/O clock high, $t_{wH}(I/O)$	200			404			ns
Pulse duration, I/O clock low, $t_{wL}(I/O)$	200			404			ns
Clock transition time (see Note 4)	System	$f_{clock(SYS)} \leq 1048$ kHz		30		30	ns
		$f_{clock(SYS)} > 1048$ kHz		20		20	
	I/O	$f_{clock(I/O)} \leq 525$ kHz		100		100	
		$f_{clock(I/O)} > 525$ kHz		40		40	
Operating free-air temperature, T_A	TLC540I, TLC541I		-40	85	-40	85	°C

- NOTES: 2. Analog input voltages greater than that applied to REF + convert as all "1"s (11111111), while input voltages less than that applied to REF- convert as all "0"s (00000000). For proper operation, REF+ voltage must be at least 1 V higher than REF- voltage. Also, the total unadjusted error may increase as this differential reference voltage falls below 4.75 V.
3. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for three SYSTEM CLOCK cycles (or less) after a chip select falling edge is detected before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum chip select setup time has elapsed.
4. This is the time required for the clock input signal to fall from V_{IH} min to V_{IL} max or to rise from V_{IL} max to V_{IH} min. In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 2 μ s for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.



TLC540I, TLC541I
8-BIT ANALOG-TO-DIGITAL CONVERTERS
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electrical characteristics over recommended operating temperature range, $V_{CC} = V_{ref+} = 4.75$ V to 5.5 V, $f_{clock(I/O)} = 2.048$ MHz for TLC540 or $f_{clock(I/O)} = 1.1$ MHz for TLC541 (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage, DATA OUT	$V_{CC} = 4.75$ V, $I_{OH} = 360$ μ A	2.4			V
V_{OL}	Low-level output voltage	$V_{CC} = 4.75$ V, $I_{OL} = 1.6$ mA			0.4	V
I_{OZ}	Off-state (high-impedance state) output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}			10	μ A
		$V_O = 0$, \overline{CS} at V_{CC}			-10	
I_{IH}	High-level input current	$V_I = V_{CC}$		0.005	2.5	μ A
I_{IL}	Low-level input current	$V_I = 0$		-0.005	-2.5	μ A
I_{CC}	Operating supply current	\overline{CS} at 0 V		1.2	2.5	mA
Selected channel leakage current		Selected channel at V_{CC} , Unselected channel at 0 V		0.4	1	μ A
		Selected channel at 0 V, Unselected channel at V_{CC}		-0.4	-1	
$I_{CC} + I_{ref}$	Supply and reference current	$V_{ref+} = V_{CC}$, \overline{CS} at 0 V		1.3	3	mA
C_i	Input capacitance	Analog inputs		7	55	pF
		Control inputs		5	15	

† All typical values are at $T_A = 25^\circ\text{C}$.

TLC540I, TLC541I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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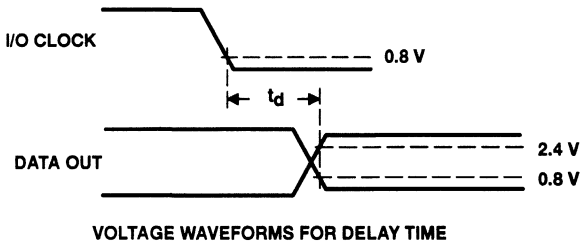
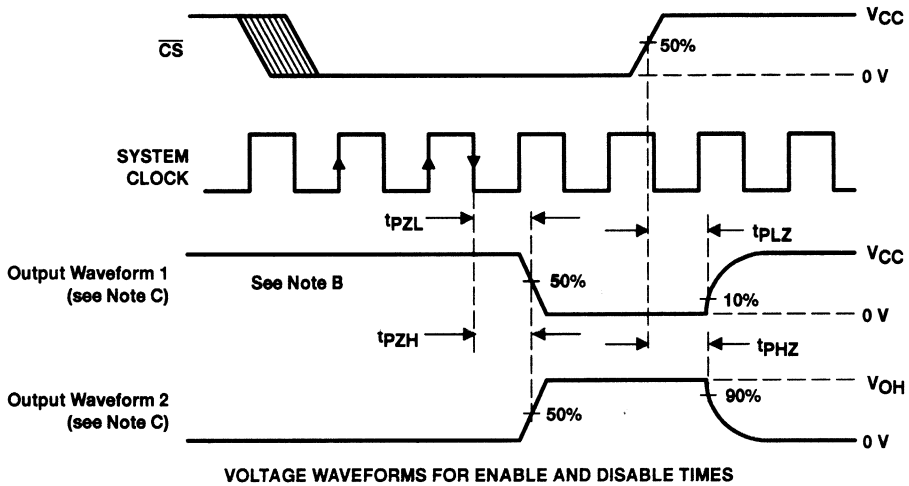
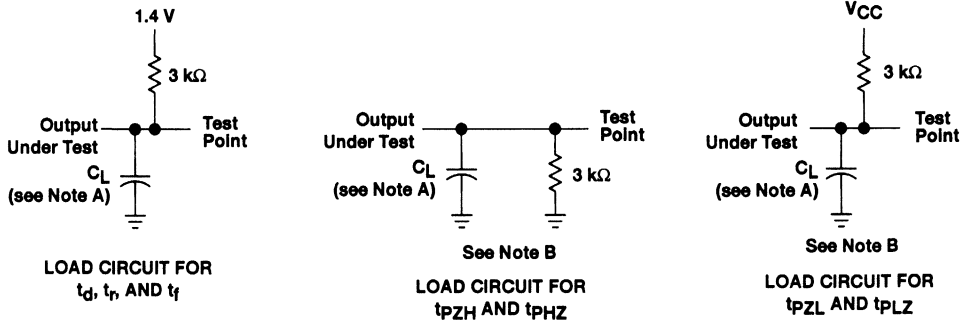
operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} - 4.75 \text{ V to } 5.5 \text{ V}$, $f_{clock(I/O)} = 2.048 \text{ MHz for TLC540 or } 1.1 \text{ MHz for TLC541}$,
 $f_{clock(SYS)} = 4 \text{ MHz for TLC540 or } 2.1 \text{ MHz for TLC541}$

PARAMETER	TEST CONDITIONS	TLC540		TLC541		UNIT
		MIN	MAX	MIN	MAX	
E_L Linearity error	See Note 5		±0.5		±0.5	LSB
E_{ZS} Zero-scale error	See Notes 2 and 6		±0.5		±0.5	LSB
E_{FS} Full-scale error	See Notes 2 and 6		±0.5		±0.5	LSB
Total unadjusted error	See Note 7		±0.5		±0.5	LSB
Self-test output code	Input A11 address = 1011, (see Note 8)	01111101 (125)	10000011 (131)	01111101 (125)	10000011 (131)	
t_{conv} Conversion time	See Operating Sequence		9		17	µs
Total access and conversion time	See Operating Sequence		13.3		25	µs
t_a Channel acquisition time (sample cycle)	See Operating Sequence		4		4	I/O clock cycles
t_v Time output data remains valid after I/O CLOCK↓		10		10		ns
t_d Delay time, I/O CLOCK↓ to data output valid	See Parameter Measurement Information		300		400	ns
t_{en} Output enable time			150		150	ns
t_{dis} Output disable time			150		150	ns
$t_r(\text{bus})$ Data bus rise time			300		300	ns
$t_f(\text{bus})$ Data bus fall time			300		300	ns

- NOTES:
- Analog input voltages greater than that applied to REF+ convert to all "1"s (11111111) while input voltages less than that applied to REF- convert to all "0"s (00000000). For proper operation, REF+ voltage must be at least 1 V higher than REF- voltage. Also, the total unadjusted error may increase as this differential reference voltage falls below 4.75 V.
 - Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
 - Zero-scale error is the difference between 00000000 and the converted output for zero input voltage; full-scale error is the difference between 11111111 and the converted output for full-scale input voltage.
 - Total unadjusted error is the sum of linearity, zero-scale, and full-scale errors.
 - Both the input address and the output codes are expressed in positive logic.



PARAMETER MEASUREMENT INFORMATION



- NOTES: A. $C_L = 50$ pF for TLC540 and 100 pF for TLC541.
 B. $t_{en} = t_{pZH}$ or t_{pZL} , $t_{dis} = t_{pHZ}$ or t_{pLZ} .
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

TLC540I, TLC541I
8-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 INPUTS

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APPLICATIONS INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 1, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/512) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/512) = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (3)$$

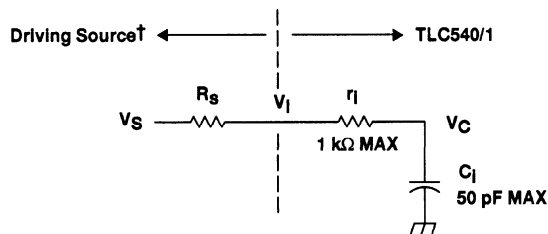
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(512) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(512) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_i = Input Voltage at INPUT A0–A10
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Equivalent Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 1. Equivalent Input Circuit Including the Driving Source

PRINCIPLES OF OPERATION

The TLC540 and TLC541 are each complete data acquisition systems on a single chip. They include such functions as analog multiplexer, sample and hold, 8-bit A/D converter, data and control registers, and control logic. For flexibility and access speed, there are four control inputs [two clocks, chip select (\overline{CS}), and address]. These control inputs and a TTL-compatible 3-state output are intended for serial communications with a microprocessor or microcomputer. With judicious interface timing, with TLC540 a conversion can be completed in 9 μ s, while complete input-conversion-output cycles can be repeated every 13 μ s. With TLC541 a conversion can be completed in 17 μ s, while complete input-conversion-output cycles are repeated every 25 μ s. Furthermore, this fast conversion can be executed on any of 11 inputs or its built-in self-test and in any order desired by the controlling processor.

The system and I/O clocks are normally used independently and do not require any special speed or phase relationships between them. This independence simplifies the hardware and software control tasks for the device. Once a clock signal within the specification range is applied to SYSTEM CLOCK, the control hardware and software need only be concerned with addressing the desired analog channel, reading the previous conversion result, and starting the conversion by using I/O CLOCK. SYSTEM CLOCK will drive the conversion crunching circuitry so that the control hardware and software need not be concerned with this task.

When \overline{CS} is high, DATA OUT is in a 3-state condition and ADDRESS INPUT and I/O CLOCK are disabled. This feature allows each of these terminals, with the exception of \overline{CS} , to share a control logic point with their counterpart terminals on additional A/D devices when additional TLC540/541 devices are used. In this way, the above feature serves to minimize the required control logic terminals when using multiple A/D devices.

The control sequence has been designed to minimize the time and effort required to initiate conversion and obtain the conversion result. A normal control sequence is:

1. \overline{CS} is brought low. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for two rising edges and then a falling edge of SYSTEM CLOCK after a low \overline{CS} transition, before the low transition is recognized. This technique is used to protect the device against noise when the device is used in a noisy environment. The MSB of the previous conversion result automatically appears on DATA OUT.
2. A new positive-logic multiplexer address is shifted in on the first four rising edges of I/O CLOCK. The MSB of the address is shifted in first. The negative edges of these four I/O clock pulses shift out the second, third, fourth, and fifth most significant bits of the previous conversion result. The on-chip sample and hold begins sampling the newly addressed analog input after the fourth falling edge. The sampling operation basically involves the charging of internal capacitors to the level of the analog input voltage.
3. Three clock cycles are then applied to I/O CLOCK and the sixth, seventh, and eighth conversion bits are shifted out on the negative edges of these clock cycles.
4. The final eighth clock cycle is applied to I/O CLOCK. The falling edge of this clock cycle completes the analog sampling process and initiates the hold function. Conversion is then performed during the next 36 system clock cycles. After this final I/O clock cycle, \overline{CS} must go high or the I/O CLOCK must remain low for at least 36 system clock cycles to allow for the conversion function.

\overline{CS} can be kept low during periods of multiple conversion. When keeping \overline{CS} low during periods of multiple conversion, special care must be exercised to prevent noise glitches on I/O CLOCK. If glitches occur on I/O CLOCK, the I/O sequence between the microprocessor/controller and the device loses synchronization. Also, if \overline{CS} is taken high, it must remain high until the end of the conversion. Otherwise, a valid falling edge of \overline{CS} causes a reset condition, which aborts the conversion in progress.

A new conversion can be started and the ongoing conversion simultaneously aborted by performing steps 1 through 4 before the 36 system clock cycles occur. Such action yields the conversion result of the previous conversion and not the ongoing conversion.

TLC540I, TLC541I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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PRINCIPLES OF OPERATION

It is possible to connect SYSTEM CLOCK and I/O clock together in special situations in which controlling circuitry points must be minimized. In this case, the following special points must be considered in addition to the requirements of the normal control sequence previously described.

1. The first two clocks are required for this device to recognize \overline{CS} is at a valid low level when the common clock signal is used as an I/O CLOCK. When \overline{CS} is recognized by the device to be at a high level, the common clock signal is used for the conversion clock also.
2. A low \overline{CS} must be recognized before the I/O CLOCK can shift in an analog channel address. The device recognizes a \overline{CS} transition when the SYSTEM CLOCK terminal receives two positive edges and then a negative edge. For this reason, after a \overline{CS} negative edge, the first two clock cycles do not shift in the address. Also, upon shifting in the address, \overline{CS} must be raised after the eighth valid (10 total) I/O CLOCK. Otherwise, additional common clock cycles are recognized as I/O CLOCKS and will shift in an erroneous address.

For certain applications, such as strobing applications, it is necessary to start conversion at a specific point in time. This device accommodates these applications. Although the on-chip sample and hold begins sampling upon the negative edge of the fourth valid I/O clock cycle, the hold function is not initiated until the negative edge of the eighth valid I/O clock cycle. Thus, the control circuitry can leave the I/O clock signal in its high state during the eighth valid I/O clock cycle until the moment at which the analog signal must be converted. The TLC540/TLC541 continues sampling the analog input until the eighth falling edge of the I/O clock. The control circuitry or software then immediately lowers the I/O clock signal and holds the analog signal at the desired point in time and start conversion.

Detailed information on interfacing to most popular microprocessors is readily available from the factory.



TLC542C, TLC542I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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- 8-Bit Resolution A/D Converter
- Microprocessor Peripheral or Stand-Alone Operation
- On-Chip 12-Channel Analog Multiplexer
- Built-In Self-Test Mode
- Software-Controllable Sample and Hold
- Total Unadjusted Error . . . ± 0.5 LSB Max
- Direct Replacement for Motorola MC145041
- On-Board System Clock
- End-of-Conversion (EOC) Output
- Pinout and Control Signals Compatible With the TLC1542/3 10-Bit A/D Converters
- CMOS Technology

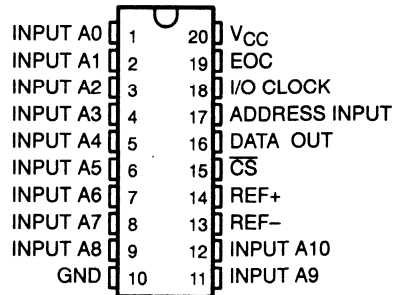
PARAMETER	VALUE
Channel Acquisition/Sample Time	16 μ s
Conversion Time (Max)	20 μ s
Samples per Second (Max)	25×10^3
Power Dissipation (Max)	10 mW

description

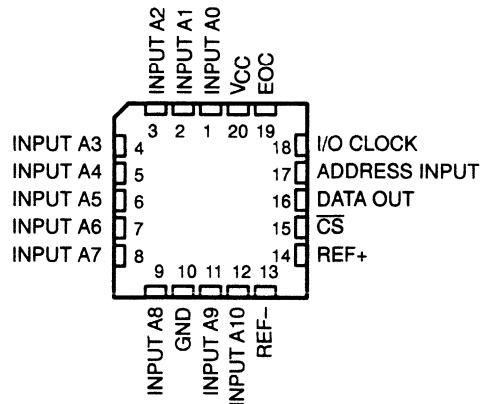
The TLC542 is a CMOS converter built around an 8-bit switched-capacitor successive-approximation analog-to-digital converter. The device is designed for serial interface to a microprocessor or peripheral via a 3-state output with three inputs [including I/O CLOCK, \overline{CS} (chip select), and ADDRESS INPUT]. The TLC542 allows high-speed data transfers and sample rates of up to 40,000 samples per second.

In addition to the high-speed converter and versatile control logic, an on-chip 12-channel analog multiplexer can sample any one of 11 inputs or an internal "self-test" voltage, and the sample and hold is started under microprocessor control. At the end of conversion, the end-of-conversion (EOC) output pin goes high to indicate that conversion is complete. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE		
	CHIP CARRIER (FN)	PLASTIC DIP (N)	SMALL OUTLINE (DW)
0°C to 70°C	TLC542CFN	TLC542CN	TLC542CDW
-40°C to 85°C	TLC542IFN	TLC542IN	TLC542IDW

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



TLC542C, TLC542I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

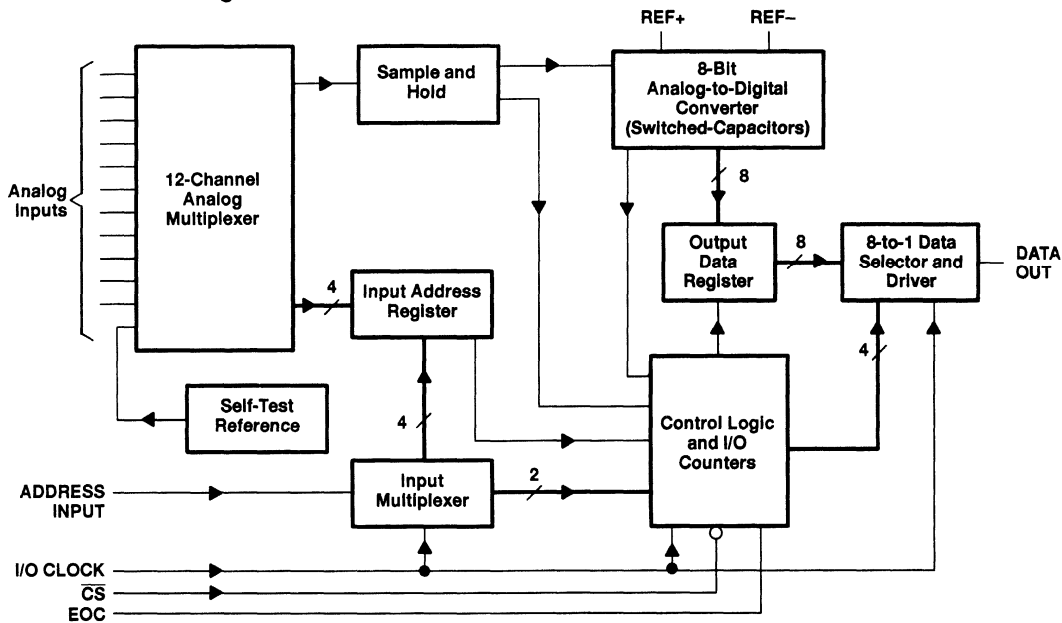
SLAS075A - FEBRUARY 1989 - REVISED MARCH 1995

description (continued)

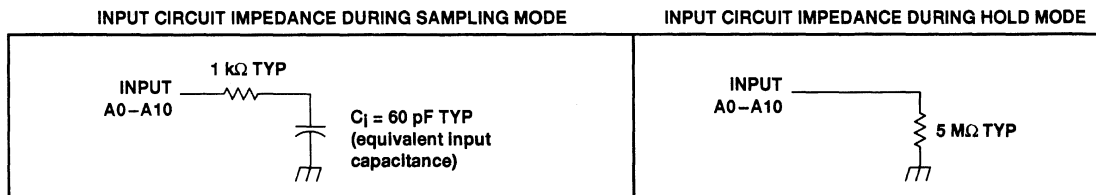
The converter incorporated in the TLC542 features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noises. A switched-capacitor design allows low-error (± 0.5 LSB) conversion in 20 μ s over the full operating temperature range.

The TLC542C is characterized for operation from 0°C to 70°C and the TLC542I is characterized for operation from -40°C to 85°C.

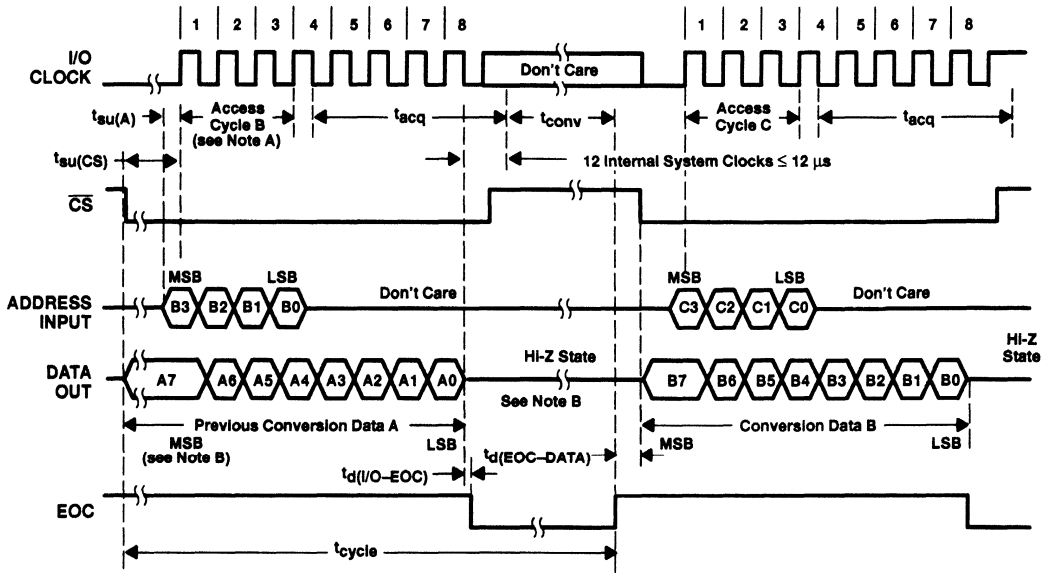
functional block diagram



typical equivalent inputs



operating sequence



- NOTES: A. To minimize errors caused by noise at the chip select input, the internal circuitry waits for two rising edges and one falling edge of the internal system clock after \overline{CS} before responding to control input signals. The \overline{CS} setup time is given by the $t_{su}(CS)$ specifications. Therefore, no attempt should be made to clock-in an address until the minimum chip select setup time has elapsed.
 B. The output is 3-stated on \overline{CS} going high or on the negative edge of the eighth I/O clock.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	6.5 V
Input voltage range (any input)	-0.3 V to $V_{CC} + 0.3$ V
Output voltage range	-0.3 V to $V_{CC} + 0.3$ V
Peak input current range (any input)	± 20 mA
Peak total input current (all inputs)	± 30 mA
Operating free-air temperature range: TLC542C	0°C to 70°C
TLC542I	-40°C to 85°C
Storage temperature range	-65°C to 150°C
Case temperature for 10 seconds: FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to digital ground with REF- and GND wired together (unless otherwise noted).

TLC542C, TLC542I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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recommended operating conditions, $V_{CC} = 4.75$ to 5.5 V

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)	V_{ref-}	V_{CC}	$V_{CC} + 0.1$	V
Negative reference voltage, V_{ref-} (see Note 2)	-0.1	0	V_{ref+}	V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)	1	V_{CC}	$V_{CC} + 0.2$	V
Analog input voltage (see Note 3)	0		V_{CC}	V
High-level control input voltage, V_{IH}	2			V
Low-level control input voltage, V_{IL}			0.8	V
Setup time, address bits at data input before I/O CLOCK \uparrow , $t_{su(A)}$	400			ns
Hold time, address bits after I/O CLOCK \uparrow , $t_h(A)$	0			ns
Hold time, \overline{CS} low after 8th I/O CLOCK \uparrow , $t_h(CS)$	0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su}(CS)$ (see Note 4)	3.8			μ s
Input/output clock frequency, $f_{clock(I/O)}$	0	1.1		MHz
Input/output clock high, $t_{wH}(I/O)$	404			ns
Input/output clock low, $t_{wL}(I/O)$	404			ns
I/O CLOCK transition time, t_t (see Note 3)	$f_{clock(I/O)} \leq 525$ kHz		100	ns
	$f_{clock(I/O)} > 525$ kHz		40	
Operating free-air temperature, T_A	TLC542C	0	70	$^{\circ}$ C
	TLC542I	-40	85	

- NOTES: 2. Analog input voltages greater than that applied to $REF+$ convert as all ones (11111111), while input voltages less than that applied to $REF-$ convert as all zeros (00000000). For proper operation, $REF+$ must be at least 1 V higher than $REF-$. Also, the total unadjusted error may increase as this differential reference voltage falls below 4.75 V.
3. This is the time required for the clock input signal to fall from V_{IH} min to V_{IL} max or to rise from V_{IL} max to V_{IH} min. In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 2 μ s for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.
4. To minimize errors caused by noise at the chip select input, the internal circuitry waits for two rising edges and one falling edge of the internal system clock after $\overline{CS} \downarrow$ before responding to control input signals. The \overline{CS} setup time is given by the $t_{su}(CS)$ specifications. Therefore, no attempt should be made to clock-in address data until the minimum chip select setup time has elapsed.

electrical characteristics over recommended operating temperature range, $V_{CC} = V_{ref+} = 4.75$ V to 5.5 V, $f_{clock(I/O)} = 1.1$ MHz (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH} High-level output voltage (DATA OUT)	$V_{CC} = 4.75$ V, $I_{OH} = -360$ μ A	2.4			V
V_{OL} Low-level output voltage	$V_{CC} = 4.75$ V, $I_{OL} = 1.6$ mA			0.4	V
Off-state (high-impedance state) output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}			10	μ A
	$V_O = 0$, \overline{CS} at V_{CC}			-10	
I_{IH} High-level input current	$V_I = V_{CC}$		0.005	2	μ A
I_{IL} Low-level input current	$V_I = 0$		-0.005	-2.5	μ A
I_{CC} Operating supply current	\overline{CS} at 0 V		1.2	2	mA
Selected channel leakage current	Selected at V_{CC} , Unselected channel at 0 V	0 $^{\circ}$ C to 70 $^{\circ}$ C		0.4	μ A
		-40 $^{\circ}$ C to 85 $^{\circ}$ C		-0.4	
I_{ref} Maximum static analog reference current into $REF+$	$V_{ref+} = V_{CC}$, $V_{ref-} = GND$			10	μ A
C_i Input capacitance	Analog inputs		7	55	pF
	Control inputs		5	15	

† All typical values are at $T_A = 25^{\circ}$ C.



TLC542C, TLC542I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.75$ to 5.5 V, $f_{clock(I/O)} = 1$ MHz

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
EL	Linearity error (see Note 5)			±0.5	LSB
EZS	Zero-scale error (see Note 6)	See Note 2		±0.5	LSB
EFS	Full-scale error (see Note 6)	See Note 2		±0.5	LSB
	Total unadjusted error (see Note 7)			±0.5	LSB
	Self-test output code	Input A11 address = 1011, See Note 8	01111101 (126)	10000011 (130)	
t_{conv}	Conversion time	See operating sequence		20	μs
t_{cycle}	Total access and conversion cycle time	See operating sequence		40	μs
t_{acq}	Channel acquisition time (sample cycle)	See operating sequence		16	μs
t_v	Time output data remains valid after I/O CLK↓	See Figure 5	10		ns
$t_d(I/O-DATA)$	Delay time, I/O CLK↓ to data output valid	See Figure 5		400	ns
$t_d(I/O-EOC)$	Delay time, 8th I/O CLK↓ to EOC↓	See Figure 6		500	ns
$t_d(EOC-DATA)$	Delay time, EOC↑ to data out (MSB)	See Figure 7		400	ns
t_{PZH}, t_{PZL}	Delay time, CS↓ to data out (MSB)	See Figure 2		3.4	μs
t_{PHZ}, t_{PLZ}	Delay time, CS↑ to data out (MSB)	See Figure 2		150	ns
$t_r(EOC)$	Rise time	See Figure 7		100	ns
$t_f(EOC)$	Fall time	See Figure 6		100	ns
$t_r(bus)$	Data bus rise time	See Figure 5		300	ns
$t_f(bus)$	Data bus fall time	See Figure 5		300	ns

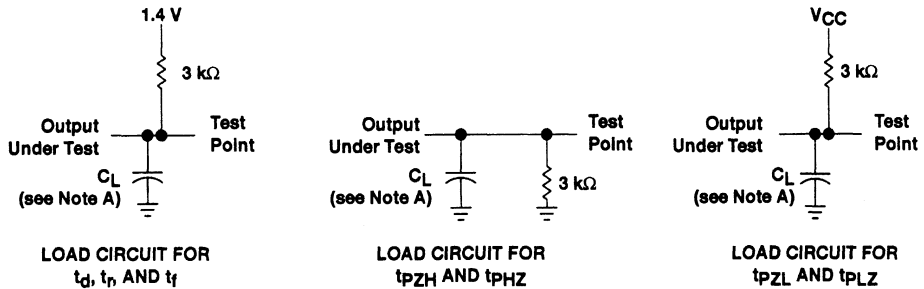
† All typical values are at $T_A = 25^\circ\text{C}$

- NOTES: 2. Analog input voltages greater than that applied to REF+ convert to all ones (11111111), while input voltages less than that applied to REF- convert to all zeros (00000000). For proper operation, REF+ must be at least 1 V higher than REF-. Also, the total unadjusted error may increase as this differential reference voltage falls below 4.75 V.
5. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
6. Zero-scale Error is the difference between 00000000 and the converted output for zero input voltage; full-scale error is the difference between 11111111 and the converted output for full-scale input voltage.
7. Total unadjusted error is the sum of linearity, zero-scale, and full-scale errors.
8. Both the input address and the output codes are expressed in positive logic. The A11 analog input signal is internally generated and is used for test purposes.

TLC542C, TLC542I
8-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 INPUTS

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PARAMETER MEASUREMENT INFORMATION



NOTE A: $C_L = 50$ pF

Figure 1. Load Circuits

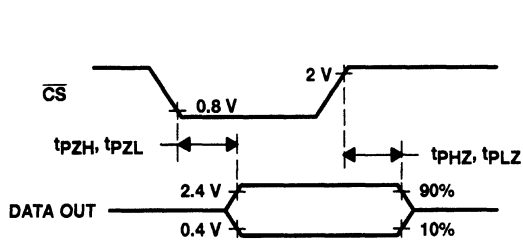


Figure 2. \overline{CS} to Data Output Timing

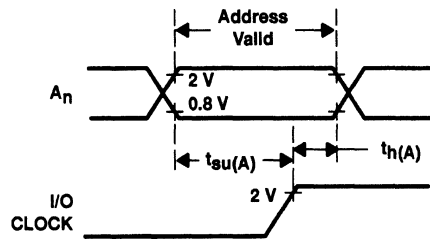


Figure 3. Address Timing

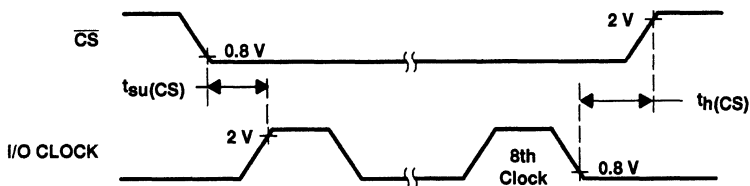


Figure 4. \overline{CS} to I/O CLOCK Timing

PARAMETER MEASUREMENT INFORMATION

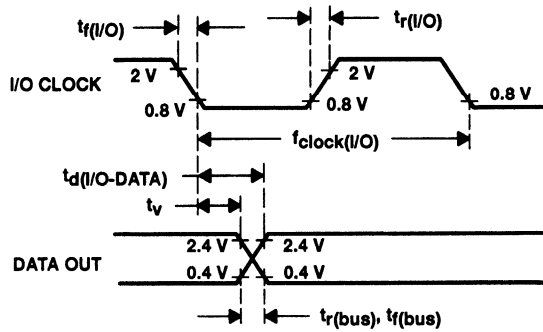


Figure 5. Data Output Timing

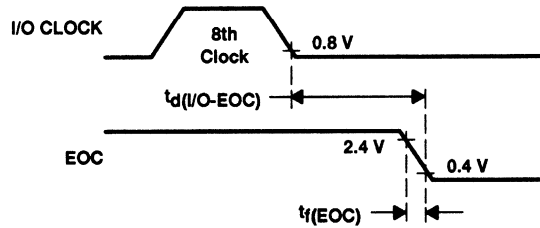


Figure 6. EOC Timing

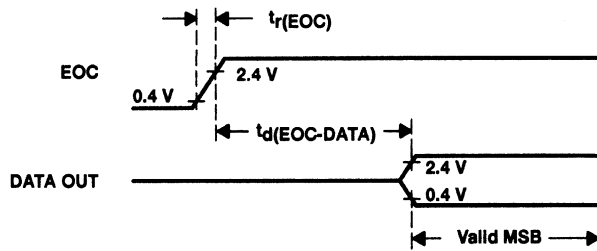


Figure 7. Data Output to EOC Timing

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APPLICATIONS INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 8, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S (1 - e^{-t_c / R_t C_i}) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/512) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/512) = V_S (1 - e^{-t_c / R_t C_i}) \quad (3)$$

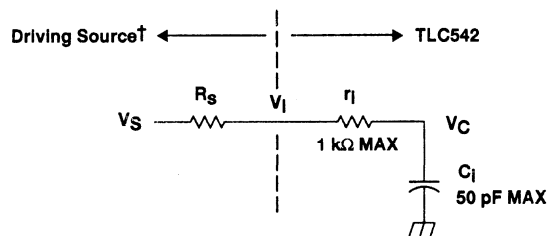
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(512) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(512) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at INPUT A0–A10
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 8. Equivalent Input Circuit Including the Driving Source

TLC542C, TLC542I
8-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 INPUTS

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PRINCIPLES OF OPERATION

The TLC542 is a complete data acquisition system on a single chip. The device includes such functions as analog multiplexer, sample and hold, 8-bit A/D converter, data and control registers, and control logic. Three control inputs (I/O CLOCK, \overline{CS} (chip select), and ADDRESS INPUT) are included for flexibility and access speed. These control inputs and a TTL-compatible 3-state output are intended for serial communications with a microprocessor or microcomputer. With judicious interface timing, the TLC542 can complete a conversion in 20 μ s, while complete input-conversion-output cycles can be repeated every 40 μ s. Furthermore, this fast conversion can be executed on any of 11 inputs or its built-in self-test and in any order desired by the controlling processor.

When \overline{CS} is high, the DATA OUT terminal is in a 3-state condition, and the ADDRESS INPUT and I/O CLOCK terminals are disabled. When additional TLC542 devices are used, this feature allows each of these terminals, with the exception of the \overline{CS} terminal, to share a control logic point with their counterpart terminals on additional A/D devices. Thus, this feature minimizes the control logic terminals required when using multiple A/D devices.

The control sequence is designed to minimize the time and effort required to initiate conversion and obtain the conversion result. A normal control sequence is as follows:

1. \overline{CS} is brought low. To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for two rising edges and then a falling edge of the internal system clock before recognizing the low \overline{CS} transition. The MSB of the result of the previous conversion automatically appears on the DATA OUT terminal.
2. On the first four rising edges of the I/O CLOCK, a new positive-logic multiplexer address is shifted in, with the MSB of this address shifted first. The negative edges of these four I/O CLOCK pulses shift out the second, third, fourth, and fifth most significant bits of the result of the previous conversion. The on-chip sample and hold begins sampling the newly addressed analog input after the fourth falling edge of the I/O CLOCK. The sampling operation basically involves charging the internal capacitors to the level of the analog input voltage.
3. Three clock cycles are applied to the I/O CLOCK terminal and the sixth, seventh, and eighth conversion bits are shifted out on the negative edges of these clock cycles.
4. The final eighth clock cycle is applied to the I/O CLOCK terminal. The falling edge of this clock cycle initiates a 12-system clock ($\approx 12 \mu$ s) additional sampling period while the output is in the high-impedance state. Conversion is then performed during the next 20 μ s. After this final I/O CLOCK cycle, \overline{CS} must go high or the I/O CLOCK must remain low for at least 20 μ s to allow for the conversion function.

\overline{CS} can be kept low during periods of multiple conversion. If \overline{CS} is taken high, it must remain high until the end of conversion. Otherwise, a valid falling edge of \overline{CS} causes a reset condition, which aborts the conversion process.

A new conversion may be started and the ongoing conversion simultaneously aborted by performing steps 1 through 4 before the 20- μ s conversion time has elapsed. Such action yields the conversion result of the previous conversion and not the ongoing conversion.

The end-of-conversion (EOC) output goes low on the negative edge of the eighth I/O CLOCK. The subsequent low-to-high transition of EOC indicates the A/D conversion is complete and the conversion is ready for transfer.

TLC545C, TLC545I, TLC546C, TLC546I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 19 INPUTS

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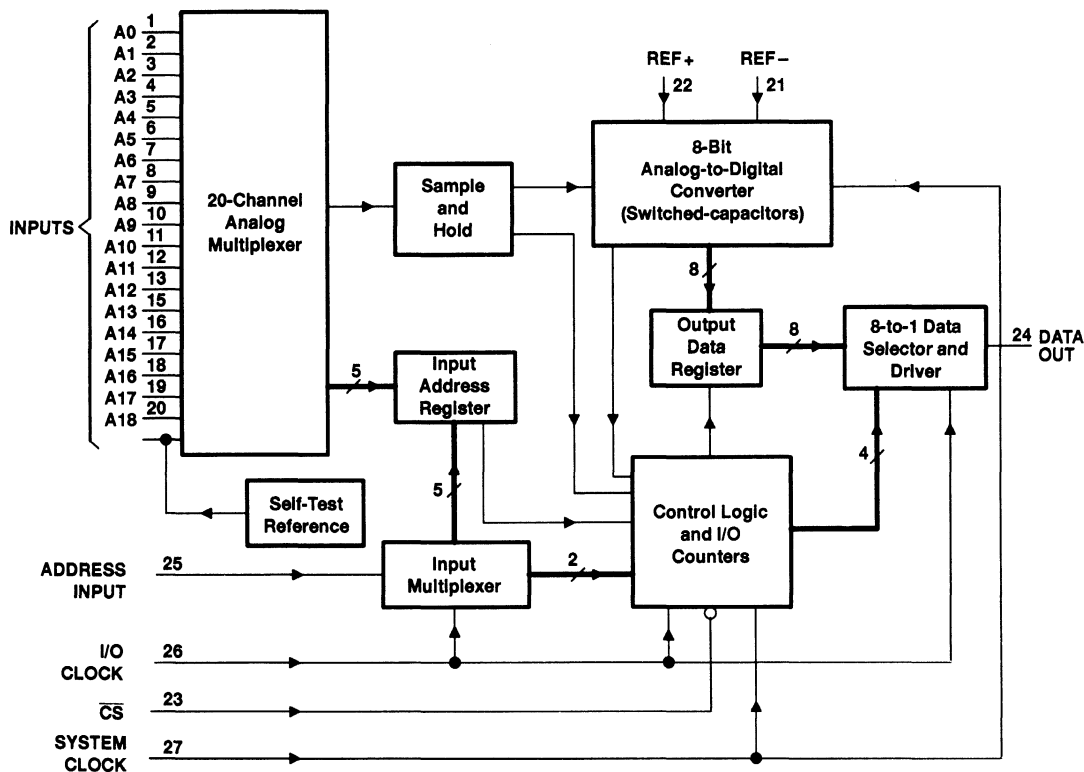
description (continued)

In addition to the high-speed converter and versatile control logic, there is an on-chip 20-channel analog multiplexer that can be used to sample any one of 19 inputs or an internal self-test voltage, and a sample-and-hold that can operate automatically or under microprocessor control.

The converters incorporated in the TLC545 and TLC546 feature differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and analog circuitry isolation from logic and supply noises. A totally switched capacitor design allows low-error (± 0.5 LSB) conversion in $9 \mu\text{s}$ for the TLC545, and $17 \mu\text{s}$ for the TLC546, over the full operating temperature range. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

The TLC545C and the TLC546C are characterized for operation from 0°C to 70°C . The TLC545I and the TLC546I are characterized for operation from -40°C to 85°C .

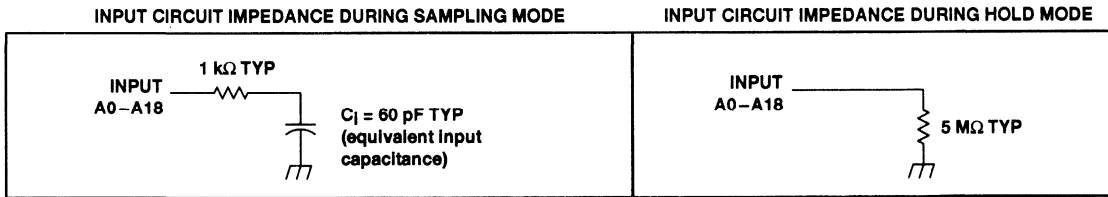
functional block diagram



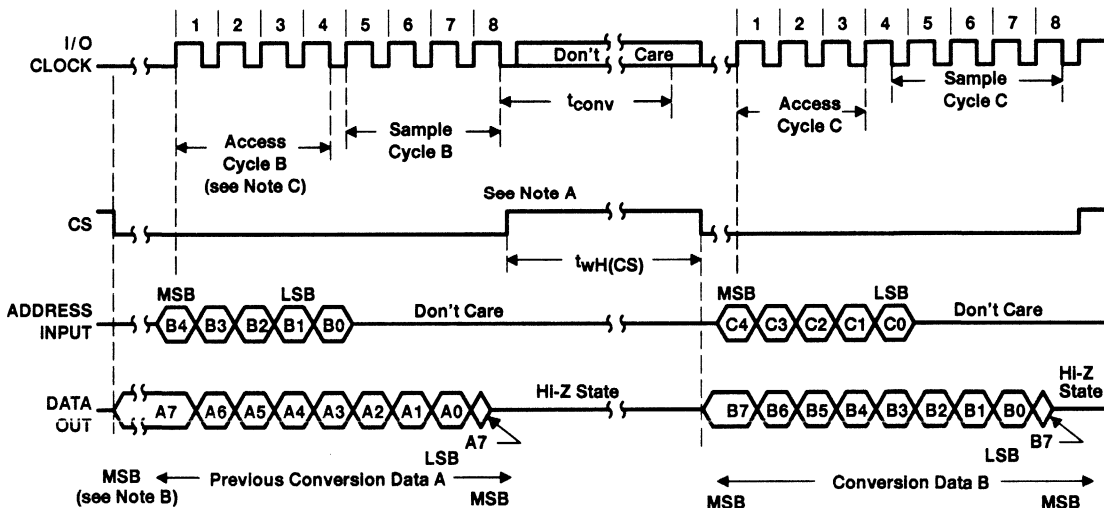
TLC545C, TLC545I, TLC546C, TLC546I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 19 INPUTS

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typical equivalent inputs



operating sequence



- NOTES:
- The conversion cycle, which requires 36 system clock periods, is initiated with the eighth I/O CLOCK \downarrow after $\overline{CS}\downarrow$ for the channel whose address exists in memory at that time.
 - The most significant bit (MSB) will automatically be placed on the DATA OUT bus after \overline{CS} is brought low. The remaining seven bits (A6-A0) will be clocked out on the first seven I/O CLOCK falling edges.
 - To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for three system clock cycles (or less) after a chip select transition before responding to control input signals. Therefore, no attempt should be made to clock-in address data until the minimum chip-select setup time has elapsed.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC} (see Note 1)	6.5 V
Input voltage range, V_I (any input)	-0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O	-0.3 V to $V_{CC} + 0.3$ V
Peak input current range (any input)	± 10 mA
Peak total input current (all inputs)	± 30 mA
Operating free-air temperature range, T_A : TLC545C, TLC546C	0°C to 70°C
TLC545I, TLC546I	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds, T_C : FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N or DW package	260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to network ground terminal.

TLC545C, TLC545I, TLC546C, TLC546I

8-BIT ANALOG-TO-DIGITAL CONVERTERS

WITH SERIAL CONTROL AND 19 INPUTS

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recommended operating conditions

	TLC545			TLC546			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	4.75	5	5.5	4.75	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)	0	V_{CC}	$V_{CC} + 0.1$	0	V_{CC}	$V_{CC} + 0.1$	V
Negative reference voltage, V_{ref-} (see Note 3)	-0.1	0	V_{CC}	-0.1	0	V_{CC}	V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 3)	0	V_{CC}	$V_{CC} + 0.2$	0	V_{CC}	$V_{CC} + 0.2$	V
Analog input voltage (see Note 3)	0		V_{CC}	0		V_{CC}	V
High-level control input voltage, V_{IH}	2			2			V
Low-level control input voltage, V_{IL}			0.8			0.8	V
Setup time, address bits at data input before I/O CLOCK \uparrow , $t_{su}(A)$	200			400			ns
Address hold time, t_h	0			0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su}(CS)$ (see Note 2)	3			3			System clock cycles
I/O CLOCK frequency, $f_{clock(I/O)}$	0		2,048	0		1.1	MHz
SYSTEM CLOCK frequency, $f_{clock(SYS)}$	$f_{clock(I/O)}$		4	$f_{clock(I/O)}$		2.1	MHz
Pulse duration, \overline{CS} high during conversion, $t_{wH}(CS)$	36			36			System clock cycles
Pulse duration, SYSTEM CLOCK high, $t_{wH}(SYS)$	110			210			ns
Pulse duration, SYSTEM CLOCK low, $t_{wL}(SYS)$	100			190			ns
Pulse duration, I/O CLOCK high, $t_{wH}(I/O)$	200			404			ns
Pulse duration, I/O CLOCK low, $t_{wL}(I/O)$	200			404			ns
Clock transition time (see Note 4)	System	$f_{clock(SYS)} \leq 1048$ kHz	30		30		ns
		$f_{clock(SYS)} > 1048$ kHz	20		20		
	I/O	$f_{clock(I/O)} \leq 525$ kHz	100		100		ns
		$f_{clock(I/O)} > 525$ kHz	40		40		
Operating free-air temperature, T_A	TLC545C, TLC546C	0	70	0	70		
	TLC545I, TLC546I	-40	85	-40	85	°C	

- NOTES: 2. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for three system clock cycles (or less) after a chip select falling edge or rising edge is detected before responding to control input signals. Therefore, no attempt should be made to clock-in address data until the minimum chip select setup time has elapsed.
3. Analog input voltages greater than that applied to REF+ convert as all "1"s (11111111), while input voltages less than that applied to REF- convert as all "0"s (00000000). As the differential reference voltage decreases below 4.75 V, the total unadjusted error tends to increase.
4. This is the time required for the clock input signal to fall from V_{IH} min to V_{IL} max or to rise from V_{IL} max to V_{IH} min. In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 2 μ s for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.

TLC545C, TLC545I, TLC546C, TLC546I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 19 INPUTS

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electrical characteristics over recommended operating temperature range,

$V_{CC} = V_{ref+} = 4.75\text{ V to }5.5\text{ V}$, $f_{clock(I/O)} = 2.048\text{ MHz}$ for TLC545 or $f_{clock(I/O)} = 1.1\text{ MHz}$ for TLC546 (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage (DATA OUT)	$V_{CC} = 4.75\text{ V}$, $I_{OH} = -360\text{ }\mu\text{A}$	2.4			V
V_{OL}	Low-level output voltage	$V_{CC} = 4.75\text{ V}$, $I_{OL} = 3.2\text{ mA}$			0.4	V
I_{OZ}	Off-state (high-impedance state) output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}			10	μA
		$V_O = 0$, \overline{CS} at V_{CC}			-10	
I_{IH}	High-level input current	$V_I = V_{CC}$		0.005	2.5	μA
I_{IL}	Low-level input current	$V_I = 0$		-0.005	-2.5	μA
I_{CC}	Operating supply current	\overline{CS} at 0 V		1.2	2.5	mA
	Selected channel leakage current	Selected channel at V_{CC} , Unselected channel at 0 V		0.4	1	μA
		Selected channel at 0 V, Unselected channel at V_{CC}		-0.4	-1	
$I_{CC} + I_{ref}$	Supply and reference current	$V_{ref+} = V_{CC}$, \overline{CS} at 0 V		1.3	3	mA
C_i	Input capacitance	Analog inputs		7	55	pF
		Control inputs		5	15	

† All typical values are at $T_A = 25^\circ\text{C}$.

operating characteristics over recommended operating free-air temperature range,

$V_{CC} = V_{ref+} = 4.75\text{ V to }5.5\text{ V}$, $f_{clock(I/O)} = 2.048\text{ MHz}$ for TLC545 or 1.1 MHz for TLC546, $f_{clock(SYS)} = 4\text{ MHz}$ for TLC545 or 2.1 MHz for TLC546

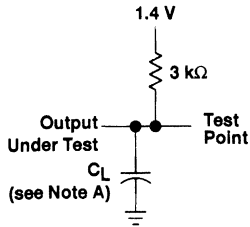
PARAMETER	TEST CONDITIONS	TLC545			TLC546			UNIT	
		MIN	TYP	MAX	MIN	TYP	MAX		
E_L	Linearity error	See Note 5			± 0.5			LSB	
E_{ZS}	Zero-scale error	See Note 6			± 0.5			LSB	
E_{FS}	Full-scale error	See Note 6			± 0.5			LSB	
	Total unadjusted error	See Note 7			± 0.5			LSB	
	Self-test output code	INPUT A19 address = 10011 (see Note 8)	01111101 (125)	10000011 (131)	01111101 (125)	10000011 (131)			
t_{conv}	Conversion time	See Operating Sequence			9			μs	
	Total access and conversion time	See Operating Sequence			13			μs	
t_{acq}	Channel acquisition time (sample cycle)	See Operating Sequence			3			I/O clock cycles	
t_v	Time output data remains valid after I/O CLOCK↓	10			10			ns	
t_d	Delay time, I/O CLOCK to DATA OUT valid	See Parameter Measurement Information			300			ns	
t_{en}	Output enable time				150			150	ns
t_{dis}	Output disable time				150			150	ns
$t_r(\text{bus})$	Data bus rise time				300			300	ns
$t_f(\text{bus})$	Data bus fall time				300			300	ns

- NOTES:
- Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
 - Zero-scale error is the difference between 00000000 and the converted output for zero input voltage; full-scale error is the difference between 11111111 and the converted output for full-scale input voltage.
 - Total unadjusted error is the sum of linearity, zero-scale, and full-scale errors.
 - Both the input address and the output codes are expressed in positive logic. The INPUT A19 analog input signal is internally generated and is used for test purposes.

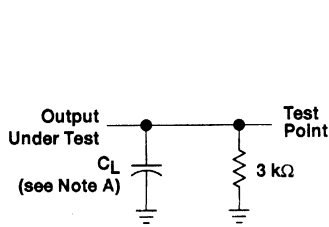
TLC545C, TLC545I, TLC546C, TLC546I
8-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 19 INPUTS

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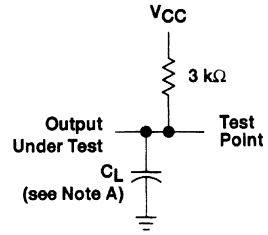
PARAMETER MEASUREMENT INFORMATION



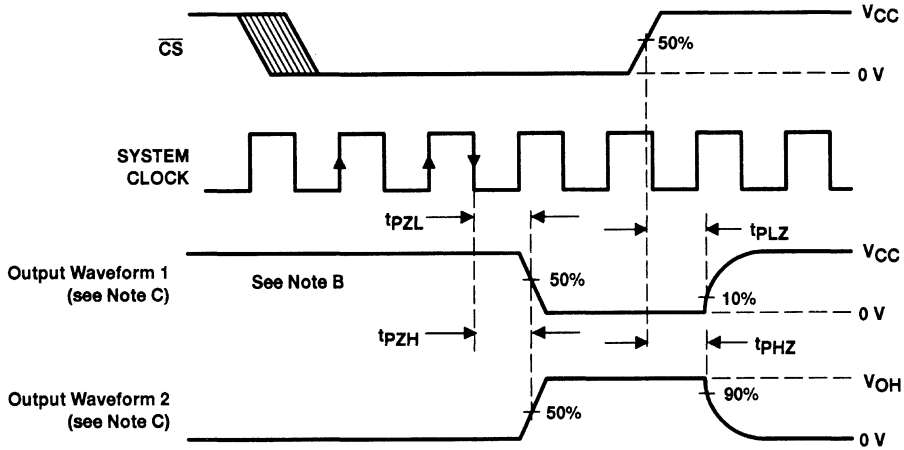
LOAD CIRCUIT FOR t_d , t_r AND t_f



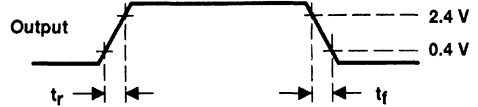
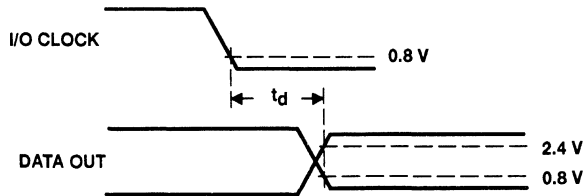
See Note B
 LOAD CIRCUIT FOR t_{pZH} AND t_{pHZ}



See Note B
 LOAD CIRCUIT FOR t_{pZL} AND t_{pLZ}



VOLTAGE WAVEFORMS FOR ENABLE AND DISABLE TIMES



VOLTAGE WAVEFORMS FOR RISE AND FALL TIMES

VOLTAGE WAVEFORMS FOR DELAY TIME

- NOTES: A. $C_L = 50$ pF for TLC545 and 100 pF for TLC546
 B. $t_{en} = t_{pZH}$ or t_{pZL} . $t_{dis} = t_{pHZ}$ or t_{pLZ}
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control.
 Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

simplified analog input analysis

Using the equivalent circuit in Figure 1, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i}\right) \tag{1}$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/512) \tag{2}$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/512) = V_S \left(1 - e^{-t_c / R_t C_i}\right) \tag{3}$$

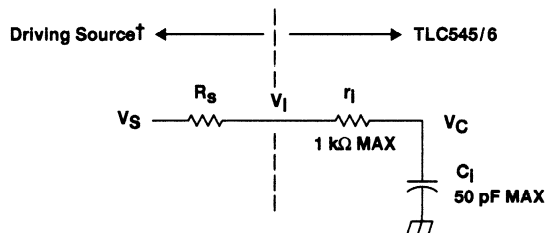
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(512) \tag{4}$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(512) \tag{5}$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at INPUT A0–A18
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 1. Equivalent Input Circuit Including the Driving Source

TLC545C, TLC545I, TLC546C, TLC546I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 19 INPUTS

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PRINCIPLES OF OPERATION

The TLC545 and TLC546 are both complete data acquisition systems on single chips. Each includes such functions as system clock, sample and hold, 8-bit A/D converter, data and control registers, and control logic. For flexibility and access speed, there are four control inputs; \overline{CS} , ADDRESS INPUT, I/O CLOCK, and SYSTEM CLOCK. These control inputs and a TTL-compatible 3-state output facilitate serial communications with a microprocessor or microcomputer. The TLC545 and TLC546 can complete conversions in a maximum of 9 and 17 μs respectively, while complete input-conversion-output cycles can be repeated at a maximum of 13 and 25 μs , respectively.

The system clock and I/O clock are normally used independently and do not require any special speed or phase relationships between them. This independence simplifies the hardware and software control tasks for the device. Once a clock signal within the specification range is applied to the SYSTEM CLOCK input, the control hardware and software need only be concerned with addressing the desired analog channel, reading the previous conversion result, and starting the conversion by using the I/O CLOCK. SYSTEM CLOCK will drive the "conversion crunching" circuitry so that the control hardware and software need not be concerned with this task.

When \overline{CS} is high, DATA OUT is in a high-impedance condition, and ADDRESS INPUT and I/O CLOCK are disabled. This feature allows each of these terminals, with the exception of \overline{CS} , to share a control logic point with their counterpart terminals on additional A/D devices when additional TLC545/TLC546 devices are used. Thus, the above feature serves to minimize the required control logic terminals when using multiple A/D devices.

The control sequence has been designed to minimize the time and effort required to initiate conversion and obtain the conversion result. A normal control sequence is:

1. \overline{CS} is brought low. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for two rising edges and then a falling edge of the SYSTEM CLOCK after a \overline{CS} transition before the transition is recognized. The MSB of the previous conversion result automatically appears on DATA OUT.
2. A new positive-logic multiplexer address is shifted in on the first five rising edges of I/O CLOCK. The MSB of the address is shifted in first. The negative edges of these five I/O clocks shift out the second, third, fourth, fifth, and sixth most significant bits of the previous conversion result. The on-chip sample and hold begins sampling the newly addressed analog input after the fifth falling edge. The sampling operation basically involves the charging of internal capacitors to the level of the analog input voltage.
3. Two clock cycles are then applied to I/O CLOCK and the seventh and eighth conversion bits are shifted out on the negative edges of these clock cycles.
4. The final eighth clock cycle is applied to I/O CLOCK. The falling edge of this clock cycle completes the analog sampling process and initiates the hold function. Conversion is then performed during the next 36 system clock cycles. After this final I/O clock cycle, \overline{CS} must go high or the I/O CLOCK must remain low for at least 36 system clock cycles to allow for the conversion function.

\overline{CS} can be kept low during periods of multiple conversion. When keeping \overline{CS} low during periods of multiple conversion, special care must be exercised to prevent noise glitches on the I/O CLOCK line. If glitches occur on the I/O CLOCK line, the I/O sequence between the microprocessor/controller and the device loses synchronization. Also, if \overline{CS} is taken high, it must remain high until the end of conversion. Otherwise, a valid falling edge of \overline{CS} causes a reset condition, which aborts the conversion in progress.

A new conversion may be started and the ongoing conversion simultaneously aborted by performing steps 1 through 4 before the 36 system clock cycles occur. Such action yields the conversion result of the previous conversion and not the ongoing conversion.



TLC545C, TLC545I, TLC546C, TLC546I
8-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 19 INPUTS

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PRINCIPLES OF OPERATION

It is possible to connect SYSTEM CLOCK and I/O CLOCK together in special situations in which controlling circuitry points must be minimized. In this case, the following special points must be considered in addition to the requirements of the normal control sequence previously described.

1. The first two clocks are required for this device to recognize \overline{CS} is at a valid low level when the common clock signal is used as an I/O CLOCK. When \overline{CS} is recognized by the device to be at a high level, the common clock signal is used for the conversion clock also.
2. A low \overline{CS} must be recognized before the I/O CLOCK can shift in an analog channel address. The device recognizes a \overline{CS} transition when the SYSTEM CLOCK terminal receives two positive edges and then a negative edge. For this reason, after a \overline{CS} negative edge, the first two clock cycles do not shift in the address. Also, upon shifting in the address, \overline{CS} must be raised after the eighth valid (10 total) I/O CLOCK. Otherwise, additional common clock cycles are recognized as I/O CLOCKS and shift in an erroneous address.

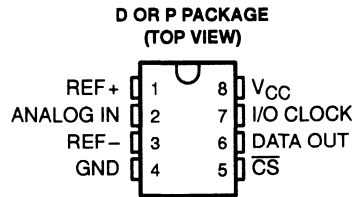
For certain applications, such as strobing applications, it is necessary to start conversion at a specific point in time. This device accommodates these applications. Although the on-chip sample and hold begins sampling upon the negative edge of the fourth valid I/O clock cycle, the hold function is not initiated until the negative edge of the eighth valid I/O clock cycle. Thus, the control circuitry can leave the I/O clock signal in its high state during the eighth valid I/O clock cycle, until the moment at which the analog signal must be converted. The TLC545/546 continues sampling the analog input until the eighth valid falling edge of the I/O clock. The control circuitry or software must then immediately lower the I/O clock signal to initiate the hold function at the desired point in time and to start conversion.

Detailed information on interfacing to most popular microprocessors is readily available from the factory.

TLC548C, TLC548I, TLC549C, TLC549I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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- Microprocessor Peripheral or Stand-Alone Operation
- 8-Bit Resolution A/D Converter
- Differential Reference Input Voltages
- Conversion Time . . . 17 μ s Max
- Total Access and Conversion Cycles Per Second
 - TLC548 . . . up to 45,500
 - TLC549 . . . up to 40,000
- On-Chip Software-Controllable Sample-and-Hold
- Total Unadjusted Error . . . ± 0.5 LSB Max
- 4-MHz Typical Internal System Clock
- Wide Supply Range . . . 3 V to 6 V
- Low Power Consumption . . . 15 mW Max
- Ideal for Cost-Effective, High-Performance Applications Including Battery-Operated Portable Instrumentation
- Pinout and Control Signals Compatible With the TLC540 and TLC545 8-Bit A/D Converters and with the TLC1540 10-Bit A/D Converter
- CMOS Technology



description

The TLC548 and TLC549 are CMOS analog-to-digital converter integrated circuits built around an 8-bit switched-capacitor successive-approximation ADC. They are designed for serial interface with a microprocessor or peripheral through a 3-state data output and an analog input. The TLC548 and TLC549 use only the input/output clock (I/O CLOCK) input along with the chip select ($\overline{\text{CS}}$) input for data control. The maximum I/O CLOCK input frequency of the TLC548 is 2.048 MHz, and the I/O CLOCK input frequency of the TLC549 is specified up to 1.1 MHz. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

Operation of the TLC548 and the TLC549 is very similar to that of the more complex TLC540 and TLC541 devices; however, the TLC548 and TLC549 provide an on-chip system clock that operates typically at 4 MHz and requires no external components. The on-chip system clock allows internal device operation to proceed independently of serial input/output data timing and permits manipulation of the TLC548 and TLC549 as desired for a wide range of software and hardware requirements. The I/O CLOCK together with the internal system clock allow high-speed data transfer and conversion rates of 45,500 conversions per second for the TLC548, and 40,000 conversions per second for the TLC549.

AVAILABLE OPTIONS

T _A	PACKAGE	
	SMALL OUTLINE (D)	PLASTIC DIP (P)
0°C to 70°C	TLC548CD TLC549CD	TLC548CP TLC549CP
-40°C to 85°C	TLC548ID TLC549ID	TLC548IP TLC549IP

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

 **TEXAS
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TLC548C, TLC548I, TLC549C, TLC549I

8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

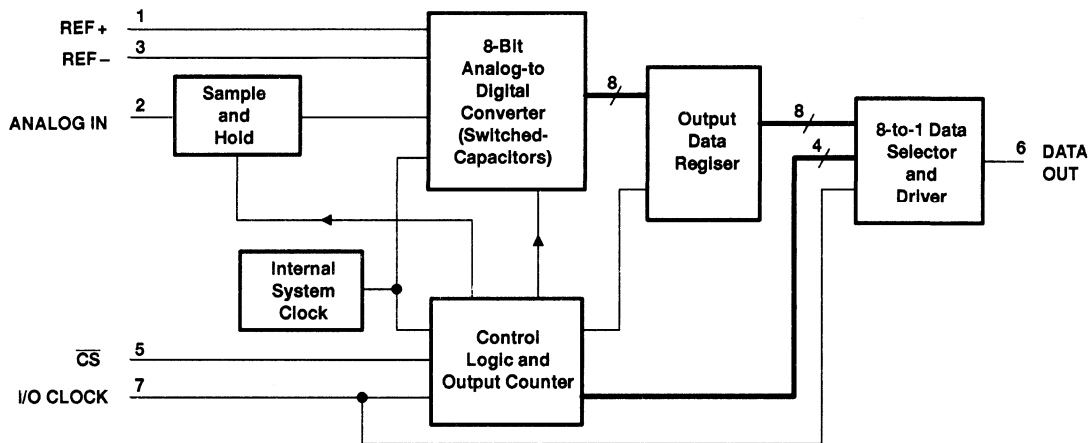
SLAS067A - NOVEMBER 1983 - REVISED MARCH 1995

description (Continued)

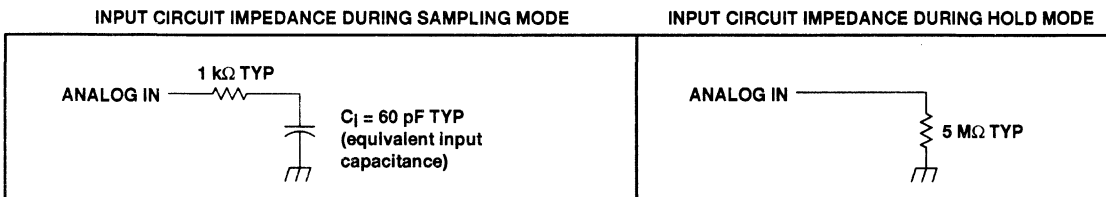
Additional TLC548 and TLC549 features include versatile control logic, an on-chip sample-and-hold circuit that can operate automatically or under microprocessor control, and a high-speed converter with differential high-impedance reference voltage inputs that ease ratiometric conversion, scaling, and circuit isolation from logic and supply noises. Design of the totally switched-capacitor successive-approximation converter circuit allows conversion with a maximum total error of ± 0.5 least significant bit (LSB) in less than $17 \mu\text{s}$.

The TLC548C and TLC549C are characterized for operation from 0°C to 70°C . The TLC548I and TLC549I are characterized for operation from -40°C to 85°C .

functional block diagram



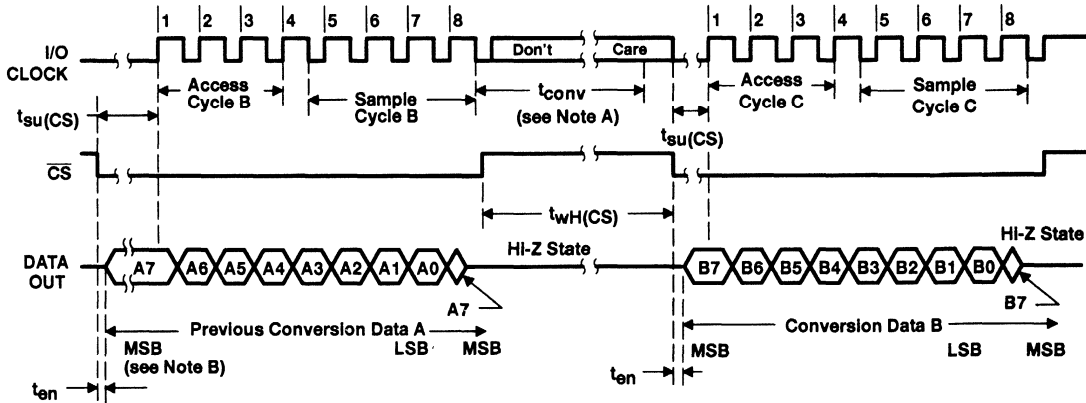
typical equivalent inputs



TLC548C, TLC548I, TLC549C, TLC549I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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operating sequence



- NOTES: A. The conversion cycle, which requires 36 internal system clock periods (17 μ s maximum), is initiated with the eighth I/O clock pulse trailing edge after \overline{CS} goes low for the channel whose address exists in memory at the time.
- B. The most significant bit (A7) will automatically be placed on the DATA OUT bus after \overline{CS} is brought low. The remaining seven bits (A6-A0) will be clocked out on the first seven I/O clock falling edges. B7-B0 will follow in the same manner.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage, V_{CC} (see Note 1)	6.5 V
Input voltage range at any input	-0.3 V to $V_{CC} + 0.3$ V
Output voltage range	-0.3 V to $V_{CC} + 0.3$ V
Peak input current range (any input)	± 10 mA
Peak total input current range (all inputs)	± 30 mA
Operating free-air temperature range, T_A (see Note 2):	TLC548C, TLC549C 0°C to 70°C
	TLC548I, TLC549I -40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

- NOTES: 1. All voltage values are with respect to the network ground terminal with the REF- and GND terminals connected together, unless otherwise noted.
2. The D package is not recommended below -40°C.

TLC548C, TLC548I, TLC549C, TLC549I

8-BIT ANALOG-TO-DIGITAL CONVERTERS

WITH SERIAL CONTROL

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recommended operating conditions

	TLC548			TLC549			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}	3	5	6	3	5	6	V
Positive reference voltage, V_{ref+} (see Note 3)	2.5	V_{CC}	$V_{CC}+0.1$	2.5	V_{CC}	$V_{CC}+0.1$	V
Negative reference voltage, V_{ref-} (see Note 3)	-0.1	0	2.5	-0.1	0	2.5	V
Differential reference voltage, V_{ref+} , V_{ref-} (see Note 3)	1	V_{CC}	$V_{CC}+0.2$	1	V_{CC}	$V_{CC}+0.2$	V
Analog input voltage (see Note 3)	0		V_{CC}	0		V_{CC}	V
High-level control input voltage, V_{IH} (for $V_{CC} = 4.75$ V to 5.5 V)	2			2			V
Low-level control input voltage, V_{IL} (for $V_{CC} = 4.75$ V to 5.5 V)			0.8			0.8	V
Input/output clock frequency, $f_{clock(I/O)}$ (for $V_{CC} = 4.75$ V to 5.5 V)	0		2.048	0		1.1	MHz
Input/output clock high, $t_{wH(I/O)}$ (for $V_{CC} = 4.75$ V to 5.5 V)	200			404			ns
Input/output clock low, $t_{wL(I/O)}$ (for $V_{CC} = 4.75$ V to 5.5 V)	200			404			ns
Input/output clock transition time, $t_t(I/O)$ (see Note 4) (for $V_{CC} = 4.75$ V to 5.5 V)			100			100	ns
Duration of \overline{CS} input high state during conversion, $t_{wH(CS)}$ (for $V_{CC} = 4.75$ V to 5.5 V)	17			17			μ s
Setup time, \overline{CS} low before first I/O CLOCK, $t_{su(CS)}$ (for $V_{CC} = 4.75$ V to 5.5 V) (see Note 5)	1.4			1.4			μ s
Operating free-air temperature, T_A	TLC548C, TLC549C		0	70	0	70	$^{\circ}$ C
	TLC548I, TLC549I		-40	85	-40	85	

- NOTES:
- Analog input voltages greater than that applied to REF+ convert to all ones (11111111), while input voltages less than that applied to REF- convert to all zeros (00000000). For proper operation, the positive reference voltage V_{ref+} must be at least 1 V greater than the negative reference voltage V_{ref-} . In addition, unadjusted errors may increase as the differential reference voltage $V_{ref+} - V_{ref-}$ falls below 4.75 V.
 - This is the time required for the input/output clock input signal to fall from V_{IH} min to V_{IL} max or to rise from V_{IL} max to V_{IH} min. In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 2 μ s for remote data acquisition applications in which the sensor and the ADC are placed several feet away from the controlling microprocessor.
 - To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for two rising edges and one falling edge of internal system clock after \overline{CS} before responding to control input signals. This \overline{CS} set-up time is given by the t_{en} and $t_{su(CS)}$ specifications.

TLC548C, TLC548I, TLC549C, TLC549I

8-BIT ANALOG-TO-DIGITAL CONVERTERS

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.75\text{ V to }5.5\text{ V}$, $f_{clock(I/O)} = 2.048\text{ MHz}$ for TLC548 or 1.1 MHz for TLC549
 (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$V_{CC} = 4.75\text{ V}$, $I_{OH} = -360\text{ }\mu\text{A}$	2.4			V
V_{OL}	Low-level output voltage	$V_{CC} = 4.75\text{ V}$, $I_{OL} = 3.2\text{ mA}$			0.4	V
I_{OZ}	Off-state (high-impedance state) output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}			10	μA
		$V_O = 0$, \overline{CS} at V_{CC}			-10	
I_{IH}	High-level input current, control inputs	$V_I = V_{CC}$		0.005	2.5	μA
I_{IL}	Low-level input current, control inputs	$V_I = 0$		-0.005	-2.5	μA
$I_{I(on)}$	Analog channel on-state input current during sample cycle	Analog input at V_{CC}		0.4	1	μA
		Analog input at 0 V		-0.4	-1	
I_{CC}	Operating supply current	\overline{CS} at 0 V		1.8	2.5	mA
$I_{CC} + I_{ref}$	Supply and reference current	$V_{ref+} = V_{CC}$		1.9	3	mA
C_i	Input capacitance	Analog inputs		7	55	pF
		Control inputs		5	15	

operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.75\text{ V to }5.5\text{ V}$, $f_{clock(I/O)} = 2.048\text{ MHz}$ for TLC548 or 1.1 MHz for TLC549
 (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC548			TLC549			UNIT	
		MIN	TYP†	MAX	MIN	TYP†	MAX		
E_L	Linearity error	See Note 6			± 0.5			LSB	
E_{ZS}	Zero-scale error	See Note 7			± 0.5			LSB	
E_{FS}	Full-scale error	See Note 7			± 0.5			LSB	
	Total unadjusted error	See Note 8			± 0.5			LSB	
t_{conv}	Conversion time	See Operating Sequence			8	17	12	17	μs
	Total access and conversion time	See Operating Sequence			12	22	19	25	μs
t_a	Channel acquisition time (sample cycle)	See Operating Sequence			4			4	I/O clock cycles
t_v	Time output data remains valid after I/O CLOCK↓	10			10			ns	
t_d	Delay time to data output valid	I/O CLOCK↓			2000			400	ns
t_{en}	Output enable time				1.4			1.4	μs
t_{dis}	Output disable time				150			150	ns
$t_{r(bus)}$	Data bus rise time	See Parameter Measurement Information			300			300	ns
$t_{f(bus)}$	Data bus fall time				300			300	ns

† All typicals are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

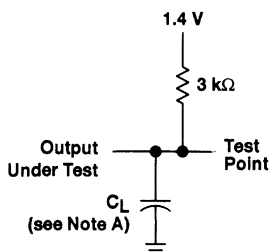
- NOTES: 6. Linearity error is the deviation from the best straight line through the A/D transfer characteristics.
 7. Zero-scale error is the difference between 00000000 and the converted output for zero input voltage; full-scale error is the difference between 11111111 and the converted output for full-scale input voltage.
 8. Total unadjusted error is the sum of linearity, zero-scale, and full-scale errors.



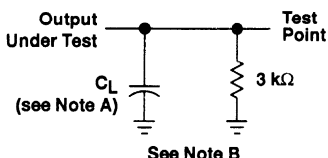
TLC548C, TLC548I, TLC549C, TLC549I 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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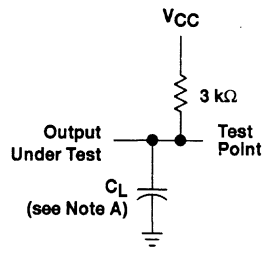
PARAMETER MEASUREMENT INFORMATION



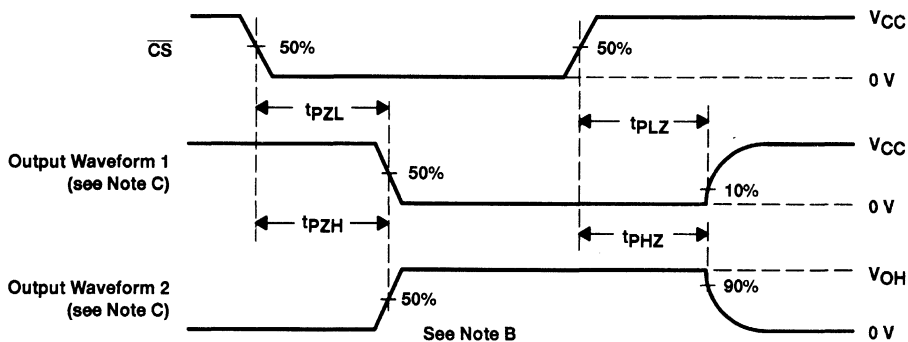
LOAD CIRCUIT FOR
 t_d , t_r , AND t_f



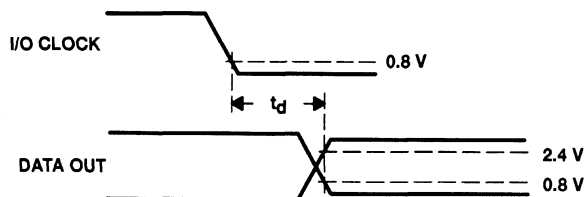
LOAD CIRCUIT FOR
 t_{pZH} AND t_{pHZ}



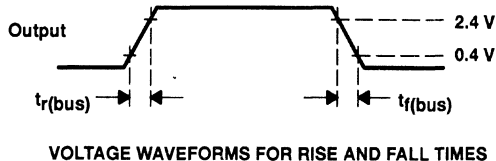
LOAD CIRCUIT FOR
 t_{pZL} AND t_{pLZ}



VOLTAGE WAVEFORMS FOR ENABLE AND DISABLE TIMES



VOLTAGE WAVEFORMS FOR DELAY TIME



VOLTAGE WAVEFORMS FOR RISE AND FALL TIMES

- NOTES: A. $C_L = 50$ pF for TLC548 and 100 pF for TLC549; C_L includes jig capacitance.
 B. $t_{en} = t_{pZH}$ or t_{pZL} , $t_{dis} = t_{pHZ}$ or t_{pLZ} .
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

APPLICATIONS INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 1, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i}\right) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/512) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/512) = V_S \left(1 - e^{-t_c / R_t C_i}\right) \quad (3)$$

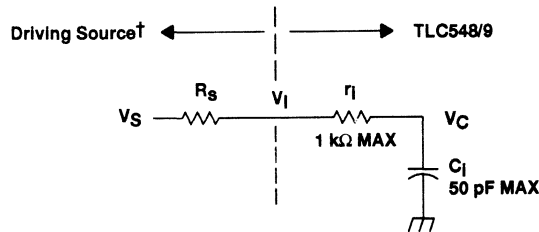
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(512) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(512) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at ANALOG IN
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 1. Equivalent Input Circuit Including the Driving Source

TLC548C, TLC548I, TLC549C, TLC549I

8-BIT ANALOG-TO-DIGITAL CONVERTERS

WITH SERIAL CONTROL

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PRINCIPLES OF OPERATION

The TLC548 and TLC549 are each complete data acquisition systems on a single chip. Each contains an internal system clock, sample and hold, 8-bit A/D converter, data register, and control logic circuitry. For flexibility and access speed, there are two control inputs: I/O CLOCK and chip select (\overline{CS}). These control inputs and a TTL-compatible 3-state output facilitate serial communications with a microprocessor or minicomputer. A conversion can be completed in 17 μ s or less, while complete input-conversion-output cycles can be repeated in 22 μ s for the TLC548 and in 25 μ s for the TLC549.

The internal system clock and I/O CLOCK are used independently and do not require any special speed or phase relationships between them. This independence simplifies the hardware and software control tasks for the device. Due to this independence and the internal generation of the system clock, the control hardware and software need only be concerned with reading the previous conversion result and starting the conversion by using the I/O clock. In this manner, the internal system clock drives the "conversion crunching" circuitry so that the control hardware and software need not be concerned with this task.

When \overline{CS} is high, DATA OUT is in a high-impedance condition and I/O CLOCK is disabled. This \overline{CS} control function allows I/O CLOCK to share the same control logic point with its counterpart terminal when additional TLC548 and TLC549 devices are used. This also serves to minimize the required control logic terminals when using multiple TLC548 and TLC549 devices.

The control sequence has been designed to minimize the time and effort required to initiate conversion and obtain the conversion result. A normal control sequence is:

1. \overline{CS} is brought low. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for two rising edges and then a falling edge of the internal system clock after a $\overline{CS}\downarrow$ before the transition is recognized. However, upon a \overline{CS} rising edge, DATA OUT will go to a high-impedance state within the t_{dis} specification even though the rest of the integrated circuitry will not recognize the transition until the $t_{su}(\overline{CS})$ specification has elapsed. This technique is used to protect the device against noise when used in a noisy environment. The most significant bit (MSB) of the previous conversion result will initially appear on DATA OUT when \overline{CS} goes low.
2. The falling edges of the first four I/O CLOCK cycles shift out the second, third, fourth, and fifth most significant bits of the previous conversion result. The on-chip sample and hold begins sampling the analog input after the fourth high-to-low transition of I/O CLOCK. The sampling operation basically involves the charging of internal capacitors to the level of the analog input voltage.
3. Three more I/O CLOCK cycles are then applied to the I/O CLOCK terminal and the sixth, seventh, and eighth conversion bits are shifted out on the falling edges of these clock cycles.
4. The final, (the eighth), clock cycle is applied to I/O CLOCK. The on-chip sample and hold begins the hold function upon the high-to-low transition of this clock cycle. The hold function will continue for the next four internal system clock cycles, after which the holding function terminates and the conversion is performed during the next 32 system clock cycles, giving a total of 36 cycles. After the eighth I/O CLOCK cycle, \overline{CS} must go high or the I/O clock must remain low for at least 36 internal system clock cycles to allow for the completion of the hold and conversion functions. \overline{CS} can be kept low during periods of multiple conversion. When keeping \overline{CS} low during periods of multiple conversion, special care must be exercised to prevent noise glitches on the I/O CLOCK line. If glitches occur on I/O CLOCK, the I/O sequence between the microprocessor/controller and the device will lose synchronization. If \overline{CS} is taken high, it must remain high until the end of conversion. Otherwise, a valid high-to-low transition of \overline{CS} will cause a reset condition, which will abort the conversion in progress.

A new conversion may be started and the ongoing conversion simultaneously aborted by performing steps 1 through 4 before the 36 internal system clock cycles occur. Such action will yield the conversion result of the previous conversion and not the ongoing conversion.



TLC548C, TLC548I, TLC549C, TLC549I
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WITH SERIAL CONTROL

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PRINCIPLES OF OPERATION

For certain applications, such as strobing applications, it is necessary to start conversion at a specific point in time. This device will accommodate these applications. Although the on-chip sample and hold begins sampling upon the high-to-low transition of the fourth I/O CLOCK cycle, the hold function does not begin until the high-to-low transition of the eighth I/O CLOCK cycle, which should occur at the moment when the analog signal must be converted. The TLC548 and TLC549 will continue sampling the analog input until the high-to-low transition of the 8th I/O CLOCK pulse. The control circuitry or software will then immediately lower I/O CLOCK and start the holding function to hold the analog signal at the desired point in time and start conversion.

Detailed information on interfacing to the most popular microprocessor is readily available from Texas Instruments.



TLC0820AC, TLC0820AI Advanced LinCMOS™ HIGH-SPEED 8-BIT ANALOG-TO-DIGITAL CONVERTERS USING MODIFIED FLASH TECHNIQUES

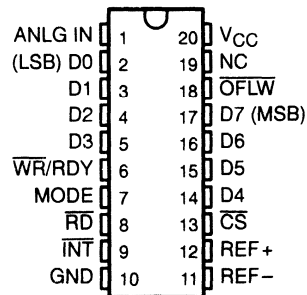
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- Advanced LinCMOS™ Silicon-Gate Technology
- 8-Bit Resolution
- Differential Reference Inputs
- Parallel Microprocessor Interface
- Conversion and Access Time Over Temperature Range
Read Mode . . . 2.5 μs Max
- No External Clock or Oscillator Components Required
- On-Chip Track and Hold
- Single 5-V Supply
- TLC0820A Is Direct Replacement for National Semiconductor ADC0820C/CC and Analog Devices AD7820K/B/T

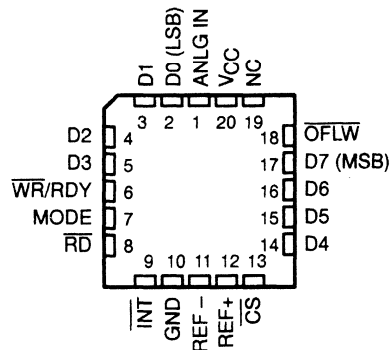
description

The TLC0820AC and the TLC0820AI are Advanced LinCMOS™ 8-bit analog-to-digital converters each consisting of two 4-bit flash converters, a 4-bit digital-to-analog converter, a summing (error) amplifier, control logic, and a result latch circuit. The modified flash technique allows low-power integrated circuitry to complete an 8-bit conversion in 1.18 μs over temperature. The on-chip track-and-hold circuit has a 100-ns sample window and allows these devices to convert continuous analog signals having slew rates of up to 100 mV/μs without external sampling components. TTL-compatible 3-state output drivers and two modes of operation allow interfacing to a variety of microprocessors. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

DB, DW, OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



NC—No internal connection

AVAILABLE OPTIONS

T _A	TOTAL UNADJUSTED ERROR	PACKAGE			
		SSOP (DB)	PLASTIC SMALL OUTLINE (DW)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	±1 LSB	TLC0820ACDB	TLC0820ACDW	TLC0820ACFN	TLC0820ACN
-40°C to 85°C	±1 LSB	TLC0820AIDB	TLC0820AIDW	TLC0820AIFN	TLC0820AIN

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PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

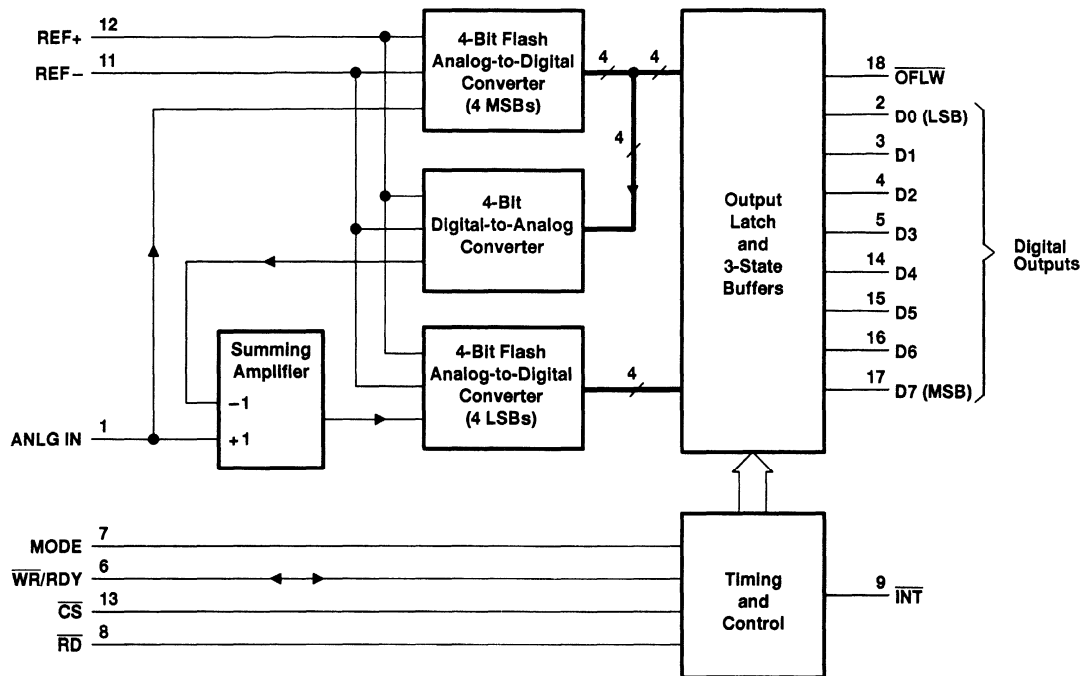


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CONVERTERS USING MODIFIED FLASH TECHNIQUES

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functional block diagram



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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANLG IN	1	I	Analog input
\overline{CS}	13	I	Chip select. \overline{CS} must be low in order for \overline{RD} or \overline{WR} to be recognized by the ADC.
D0	2	O	Digital, 3-state output data, bit 1 (LSB)
D1	3	O	Digital, 3-state output data, bit 2
D2	4	O	Digital, 3-state output data, bit 3
D3	5	O	Digital, 3-state output data, bit 4
D4	14	O	Digital, 3-state output data, bit 5
D5	15	O	Digital, 3-state output data, bit 6
D6	16	O	Digital, 3-state output data, bit 7
D7	17	O	Digital, 3-state output data, bit 8 (MSB)
GND	10		Ground
\overline{INT}	9	O	Interrupt. In the write-read mode, the interrupt output (\overline{INT}) going low indicates that the internal count-down delay time, $t_{d(int)}$, is complete and the data result is in the output latch. The delay time $t_{d(int)}$ is typically 800 ns starting after the rising edge of \overline{WR} (see operating characteristics and Figure 3). If \overline{RD} goes low prior to the end of $t_{d(int)}$, \overline{INT} goes low at the end of $t_{d(RIL)}$ and the conversion results are available sooner (see Figure 2). \overline{INT} is reset by the rising edge of either \overline{RD} or \overline{CS} .
MODE	7	I	Mode select. MODE is internally tied to GND through a 50- μ A current source, which acts like a pulldown resistor. When MODE is low, the read mode is selected. When MODE is high, the write-read mode is selected.
NC	19		No internal connection
\overline{OFLW}	18	O	Overflow. Normally \overline{OFLW} is a logical high. However, if the analog input is higher than V_{ref+} , \overline{OFLW} will be low at the end of conversion. It can be used to cascade two or more devices to improve resolution (9 or 10 bits).
\overline{RD}	8	I	Read. In the write-read mode with \overline{CS} low, the 3-state data outputs D0 through D7 are activated when \overline{RD} goes low. \overline{RD} can also be used to increase the conversion speed by reading data prior to the end of the internal count-down delay time. As a result, the data transferred to the output latch is latched after the falling edge of \overline{RD} . In the read mode with \overline{CS} low, the conversion starts with \overline{RD} going low. \overline{RD} also enables the 3-state data outputs on completion of the conversion. RDY going into the high-impedance state and \overline{INT} going low indicate completion of the conversion.
REF-	11	I	Reference voltage. REF- is placed on the bottom of the resistor ladder.
REF+	12	I	Reference voltage. REF+ is placed on the top of the resistor ladder.
VCC	20		Power supply voltage
\overline{WR}/RDY	6	I/O	Write ready. In the write-read mode with \overline{CS} low, the conversion is started on the falling edge of the \overline{WR} input signal. The result of the conversion is strobed into the output latch after the internal count-down delay time, $t_{d(int)}$, provided that the \overline{RD} input does not go low prior to this time. The delay time $t_{d(int)}$ is approximately 800 ns. In the read mode, RDY (an open-drain output) goes low after the falling edge of \overline{CS} and goes into the high-impedance state when the conversion is strobed into the output latch. It is used to simplify the interface to a microprocessor system.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	10 V
Input voltage range, all inputs (see Note 1)	-0.2 V to $V_{CC}+0.2$ V
Output voltage range, all outputs (see Note 1)	-0.2 V to $V_{CC}+0.2$ V
Operating free-air temperature range:	
TLC0820AC	0°C to 70°C
TLC0820AI	-40°C to 85°C
Storage temperature range	-65°C to 150°C
Case temperature for 10 seconds: FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DB, DW or N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltages are with respect to network GND.

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	8	V
Analog input voltage		-0.1		$V_{CC}+0.1$	V
Positive reference voltage, V_{ref+}		V_{ref-}		V_{CC}	V
Negative reference voltage, V_{ref-}		GND		V_{ref+}	V
High-level input voltage, V_{IH}	$V_{CC} = 4.75$ V to 5.25 V	$\overline{CS}, \overline{WR/RDY}, \overline{RD}$	2		V
		MODE	3.5		
Low-level input voltage, V_{IL}	$V_{CC} = 4.75$ V to 5.25 V	$\overline{CS}, \overline{WR/RDY}, \overline{RD}$	0.8		V
		MODE	1.5		
Pulse duration, write in write-read mode, $t_w(W)$ (see Figures 2, 3, and 4)		0.5		50	μ s
Operating free-air temperature, T_A	TLC0820AC	0		70	°C
	TLC0820AI	-40		85	

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electrical characteristics at specified operating free-air temperature, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	T_A^\dagger	MIN	TYP	MAX	UNIT	
V_{OH}	High-level output voltage	D0–D7, \overline{INT} , or \overline{OFLW}	Full range	$V_{CC} = 4.75\text{ V}$, $I_{OH} = -360\ \mu\text{A}$	2.4		V	
				$V_{CC} = 4.75\text{ V}$, $I_{OH} = -10\ \mu\text{A}$	Full range	4.5		
			25°C	4.6				
V_{OL}	Low-level output voltage	D0–D7, \overline{OFLW} , \overline{INT} , or $\overline{WR/RDY}$	Full range	$V_{CC} = 5.25\text{ V}$, $I_{OL} = 1.6\text{ mA}$	0.4		V	
					25°C	0.34		
I_{IH}	High-level input current	\overline{CS} or \overline{RD}	Full range	$V_{IH} = 5\text{ V}$	0.005		μA	
					25°C	3		
						Full range		0.1
					25°C			200
I_{IL}	Low-level input current	\overline{CS} , $\overline{WR/RDY}$, \overline{RD} , or MODE	Full range	$V_{IL} = 0$	-0.005		μA	
					-1			
I_{OZ}	Off-state (high-impedance-state) output current	D0–D7 or $\overline{WR/RDY}$	Full range	$V_O = 5\text{ V}$	3		μA	
					25°C	0.1		0.3
			Full range	$V_O = 0$	-3			
					25°C	-0.1		-0.3
I_I	Analog input current		Full range	CS at 5 V, $V_I = 5\text{ V}$	3		μA	
					25°C	0.3		
			Full range	CS at 5 V, $V_I = 0$	-3			
					25°C	-0.3		
I_{OS}	Short-circuit output current	D0–D7, \overline{OFLW} , \overline{INT} , or $\overline{WR/RDY}$	Full range	$V_O = 5\text{ V}$	7		mA	
					25°C	8.4		14
		D0–D7 or \overline{OFLW}	Full range	$V_O = 0$	-6			
					25°C	-7.2		-12
		INT	Full range	$V_O = 0$	-4.5			
					25°C	-5.3		-9
R_{ref}	Reference resistance		Full range	1.25		k Ω		
				25°C	1.4		2.3	5.3
I_{CC}	Supply current		Full range	\overline{CS} , $\overline{WR/RDY}$, and \overline{RD} at 0 V	15		mA	
					25°C	7.5		13
C_i	Input capacitance	D0–D7	Full range	5		pF		
		ANLG IN		45				
C_o	Output capacitance	D0–D7	Full range	5		pF		

† Full range is as specified in recommended operating conditions.



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operating characteristics, $V_{CC} = 5\text{ V}$, $V_{ref+} = 5\text{ V}$, $V_{ref-} = 0$, $t_r = t_f = 20\text{ ns}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	MIN	TYP	MAX	UNIT
k_{SVS}	Supply-voltage sensitivity	$V_{CC} = 5\text{ V} \pm 5\%$, $T_A = \text{MIN to MAX}$		$\pm 1/16$	$\pm 1/4$	LSB
	Total unadjusted error‡	MODE at 0 V, $T_A = \text{MIN to MAX}$			1	LSB
$t_{conv(R)}$	Conversion time, read mode	MODE at 0 V, See Figure 1		1.6	2.5	μs
$t_{a(R)}$	Access time, $\overline{RD}\downarrow$ to data valid	MODE at 0 V, See Figure 1		$t_{conv(R)+20}$	$t_{conv(R)+50}$	ns
$t_{a(R1)}$	Access time, $\overline{RD}\downarrow$ to data valid	MODE at 5 V, $t_d(WR) < t_d(int)$, See Figure 2	$C_L = 15\text{ pF}$	190	280	ns
			$C_L = 100\text{ pF}$	210	320	
$t_{a(R2)}$	Access time, $\overline{RD}\downarrow$ to data valid	MODE at 5 V, $t_d(WR) > t_d(int)$, See Figure 3	$C_L = 15\text{ pF}$	70	120	ns
			$C_L = 100\text{ pF}$	90	150	
$t_{a(INT)}$	Access time, $\overline{INT}\downarrow$ to data valid	MODE at 5 V, See Figure 4		20	50	ns
t_{dis}	Disable time, $\overline{RD}\uparrow$ to data valid	$R_L = 1\text{ k}\Omega$, $C_L = 10\text{ pF}$, See Figures 1, 2, 3, and 5		70	95	ns
$t_{d(int)}$	Delay time, $\overline{WR/RDY}\uparrow$ to $\overline{INT}\downarrow$	MODE at 5 V, $C_L = 50\text{ pF}$, See Figures 2, 3, and 4		800	1300	ns
$t_{d(NC)}$	Delay time, to next conversion	See Figures 1, 2, 3, and 4	500			ns
$t_{d(WR)}$	Delay time, $\overline{WR/RDY}\uparrow$ to $\overline{RD}\downarrow$ in write-read mode	See Figure 2	0.4			μs
$t_{d(RDY)}$	Delay time, $\overline{CS}\downarrow$ to $\overline{WR/RDY}\downarrow$	MODE at 0 V, See Figure 1		50	100	ns
$t_{d(RIH)}$	Delay time, $\overline{RD}\uparrow$ to $\overline{INT}\uparrow$	$C_L = 50\text{ pF}$, See Figures 1, 2, and 3		125	225	ns
$t_{d(RIL)}$	Delay time, $\overline{RD}\downarrow$ to $\overline{INT}\downarrow$	MODE at 5 V, See Figure 2		200	290	ns
$t_{d(WIH)}$	Delay time, $\overline{WR/RDY}\uparrow$ to $\overline{INT}\uparrow$	MODE at 5 V, See Figure 4		175	270	ns
	Slew-rate tracking			0.1		V/ μs

† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

‡ Total unadjusted error includes offset, full-scale, and linearity errors.



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PARAMETER MEASUREMENT INFORMATION

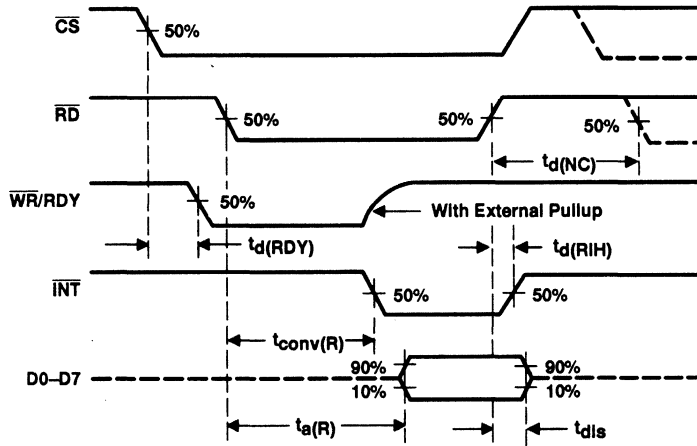


Figure 1. Read-Mode Waveforms (MODE Low)

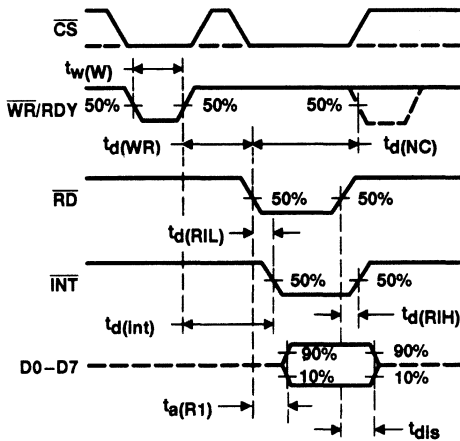


Figure 2. Write-Read-Mode Waveforms
[MODE High and $t_d(WR) < t_d(INT)$]

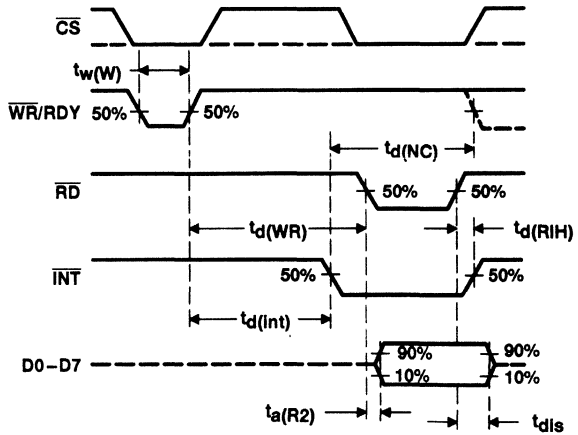


Figure 3. Write-Read-Mode Waveforms
[MODE High and $t_d(WR) > t_d(INT)$]

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PARAMETER MEASUREMENT INFORMATION

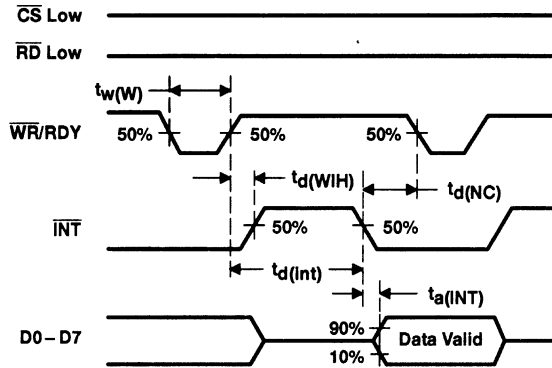
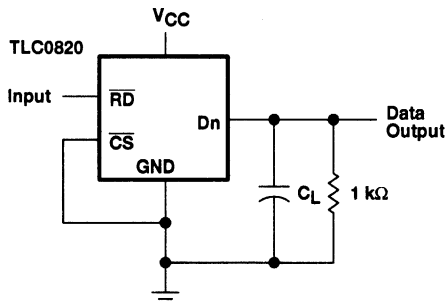
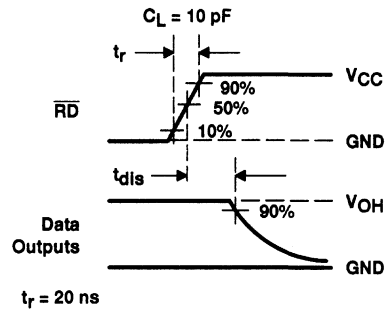


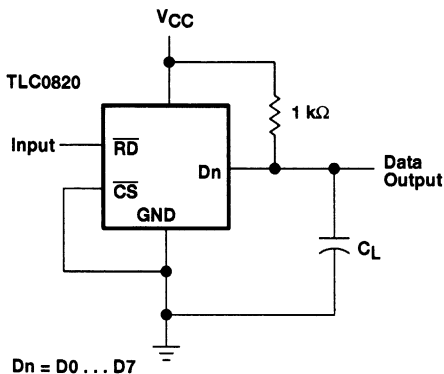
Figure 4. Write-Read-Mode Waveforms
(Stand-Alone Operation, MODE High, and RD Low)



TEST CIRCUIT

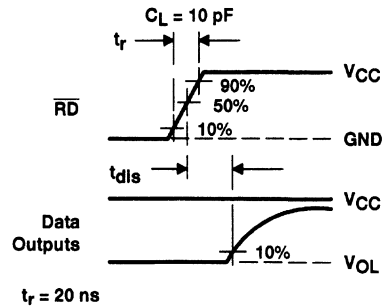


VOLTAGE WAVEFORMS



Dn = D0 . . . D7

TEST CIRCUIT



VOLTAGE WAVEFORMS

Figure 5. Test Circuit and Voltage Waveforms

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PRINCIPLES OF OPERATION

The TLC0820AC and TLC0820AI each employ a combination of sampled-data comparator techniques and flash techniques common to many high-speed converters. Two 4-bit flash analog-to-digital conversions are used to give a full 8-bit output.

The recommended analog input voltage range for conversion is -0.1 V to $V_{CC} + 0.1\text{ V}$. Analog input signals that are less than $V_{ref-} + 1/2\text{ LSB}$ or greater than $V_{ref+} - 1/2\text{ LSB}$ convert to 00000000 or 11111111, respectively. The reference inputs are fully differential with common-mode limits defined by the supply rails. The reference input values define the full-scale range of the analog input. This allows the gain of the ADC to be varied for ratiometric conversion by changing the V_{ref+} and V_{ref-} voltages.

The device operates in two modes, read (only) and write-read, that are selected by MODE. The converter is set to the read (only) mode when MODE is low. In the read mode, \overline{WR}/RDY is used as an output and is referred to as the ready terminal. In this mode, a low on \overline{WR}/RDY while \overline{CS} is low indicates that the device is busy. Conversion starts on the falling edge of \overline{RD} and is completed no more than $2.5\text{ }\mu\text{s}$ later when \overline{INT} falls and \overline{WR}/RDY returns to the high-impedance state. Data outputs also change from high-impedance to active states at this time. After the data is read, \overline{RD} is taken high, \overline{INT} returns high, and the data outputs return to their high-impedance states.

When MODE is high, the converter is set to the write-read mode and \overline{WR}/RDY is referred to as the write terminal. Taking \overline{CS} and \overline{WR}/RDY low selects the converter and initiates measurement of the input signal. Approximately 600 ns after \overline{WR}/RDY returns high, the conversion is completed. Conversion starts on the rising edge of \overline{WR}/RDY in the write-read mode.

The high-order 4-bit flash ADC measures the input by means of 16 comparators operating simultaneously. A high-precision 4-bit DAC then generates a discrete analog voltage from the result of that conversion. After a time delay, a second bank of comparators does a low-order conversion on the analog difference between the input level and the high-order DAC output. The results from each of these conversions enter an 8-bit latch and are output to the 3-state output buffers on the falling edge of \overline{RD} .

APPLICATION INFORMATION

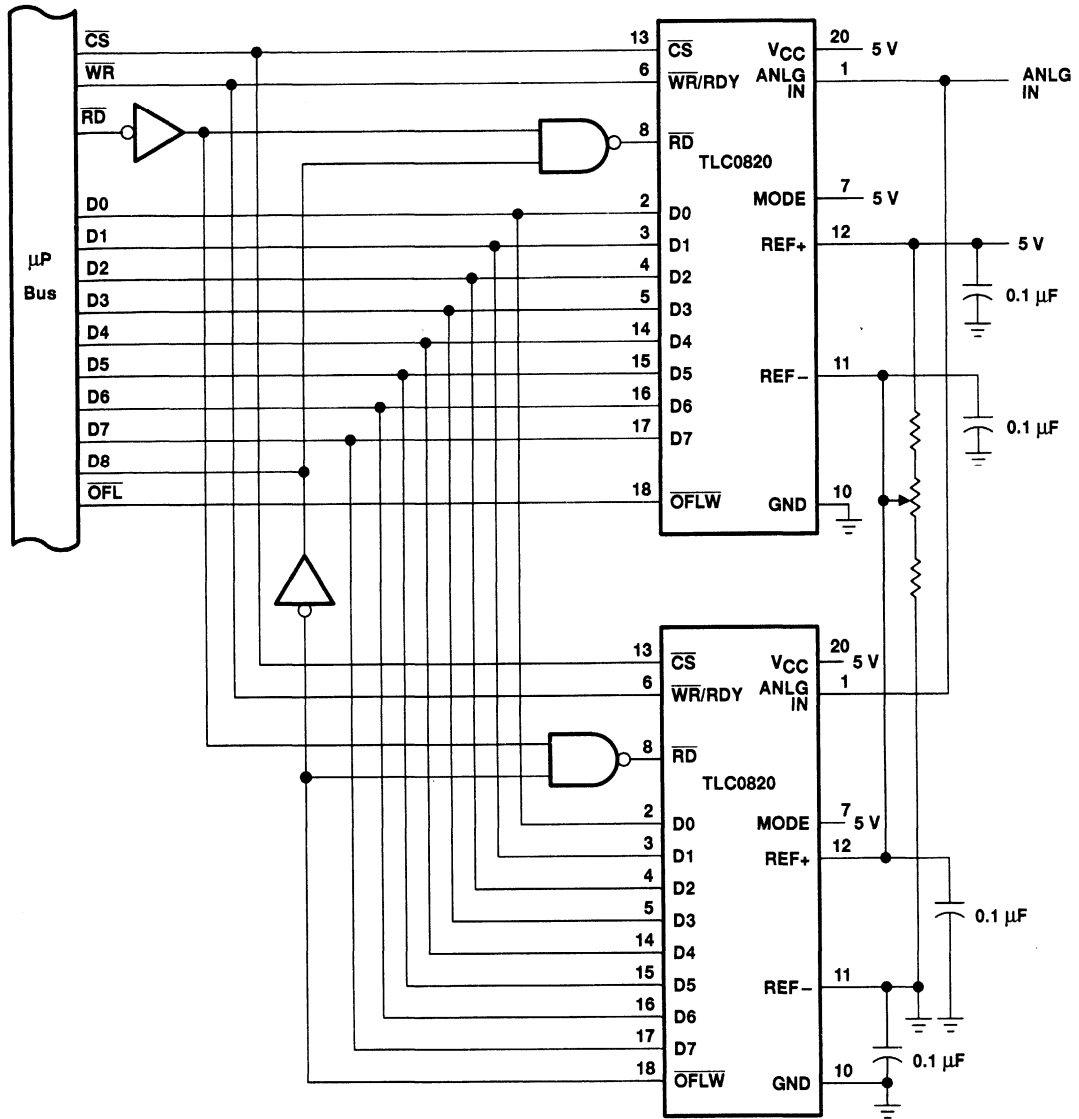


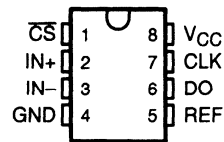
Figure 6. Configuration for 9-Bit Resolution

TLC0831AC, TLC0831AI, TLC0831BC, TLC0831BI TLC0832AC, TLC0832AI, TLC0832BC, TLC0832BI 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

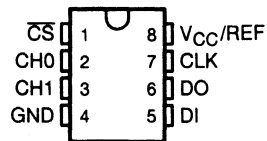
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- **8-Bit Resolution**
- **Easy Microprocessor Interface or Stand-Alone Operation**
- **Operates Ratiometrically or With 5-V Reference**
- **Single Channel or Multiplexed Twin Channels With Single-Ended or Differential Input Options**
- **Input Range 0 to 5 V With Single 5-V Supply**
- **Inputs and Outputs Are Compatible With TTL and MOS**
- **Conversion Time of 32 μ s at $f_{\text{clock}} = 250$ kHz**
- **Designed to Be Interchangeable With National Semiconductor ADC0831 and ADC0832**

TLC0831 . . . D OR P PACKAGE
(TOP VIEW)



TLC0832 . . . D OR P PACKAGE
(TOP VIEW)



DEVICE	TOTAL UNADJUSTED ERROR	
	A-SUFFIX	B-SUFFIX
TLC0831	± 1 LSB	$\pm 1/2$ LSB
TLC0832	± 1 LSB	$\pm 1/2$ LSB

description

These devices are 8-bit successive-approximation analog-to-digital converters. The TLC0831 has single input channels; the TLC0832 has multiplexed twin input channels. The serial output is configured to interface with standard shift registers or microprocessors. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

The TLC0832 multiplexer is software configured for single-ended or differential inputs. The differential analog voltage input allows for common-mode rejection or offset of the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding any smaller analog voltage span to the full 8 bits of resolution.

The operation of the TLC0831 and TLC0832 devices is very similar to the more complex TLC0834 and TLC0838 devices. Ratiometric conversion can be attained by setting the REF input equal to the maximum analog input signal value, which gives the highest possible conversion resolution. Typically, REF is set equal to V_{CC} (done internally on the TLC0832). For more detail on the operation of the TLC0831 and TLC0832 devices, refer to the TLC0834/TLC0838 data sheet.

The TLC0831AC, TLC0831BC, TLC0832AC, and TLC0832BC are characterized for operation from 0°C to 70°C. The TLC0831AI, TLC0831BI, TLC0832AI, and TLC0832BI are characterized for operation from -40°C to 85°C.

AVAILABLE OPTIONS

T _A	PACKAGE			
	SMALL OUTLINE (D)		PLASTIC DIP (P)	
0°C to 70°C	TLC0831ACP TLC0831BCP	TLC0832ACP TLC0832BCP	TLC0831ACP TLC0831BCP	TLC0832ACP TLC0832BCP
-40°C to 85°C	TLC0831AIP TLC0831BIP	TLC0832AIP TLC0832BIP	TLC0831AIP TLC0831BIP	TLC0832AIP TLC0832BIP

PRODUCT PREVIEW

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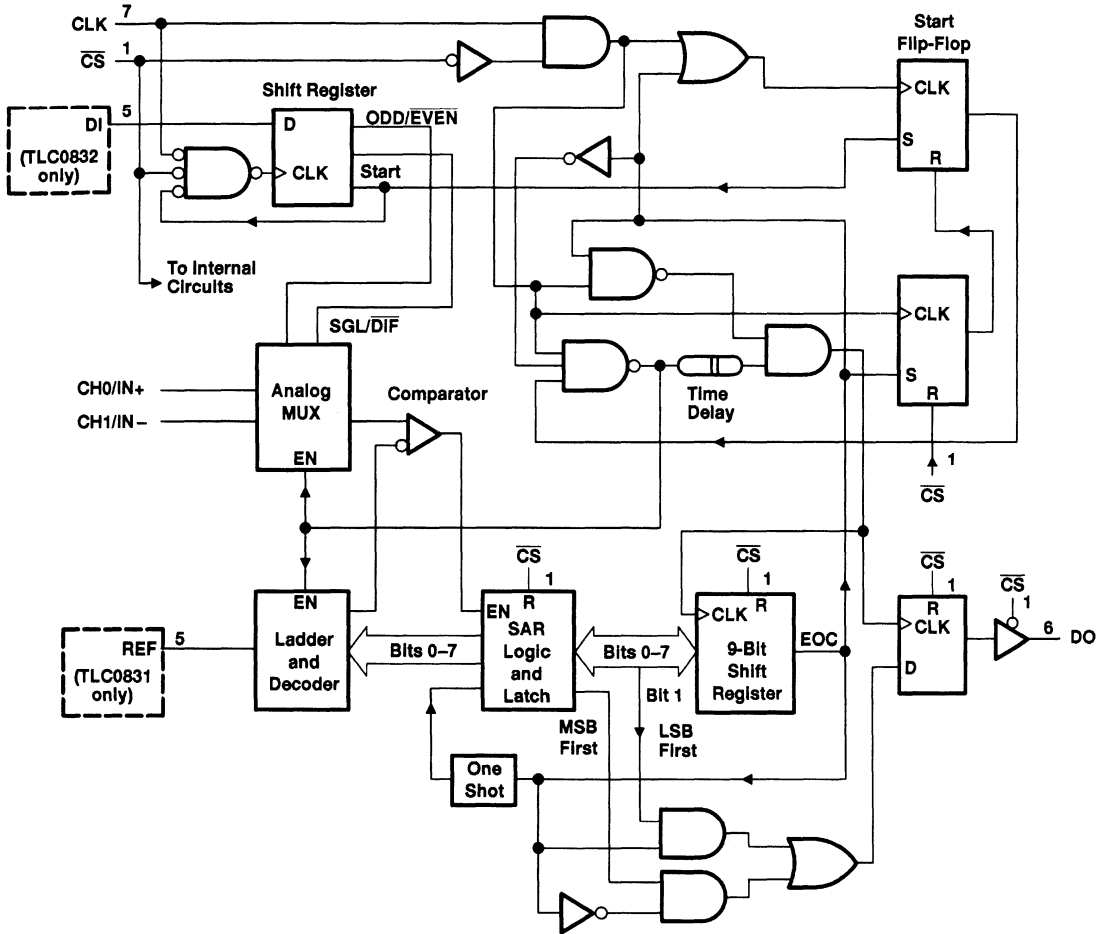


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TLC0831AC, TLC0831AI, TLC0831BC, TLC0831BI
 TLC0832AC, TLC0832AI, TLC0832BC, TLC0832BI
 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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functional block diagram



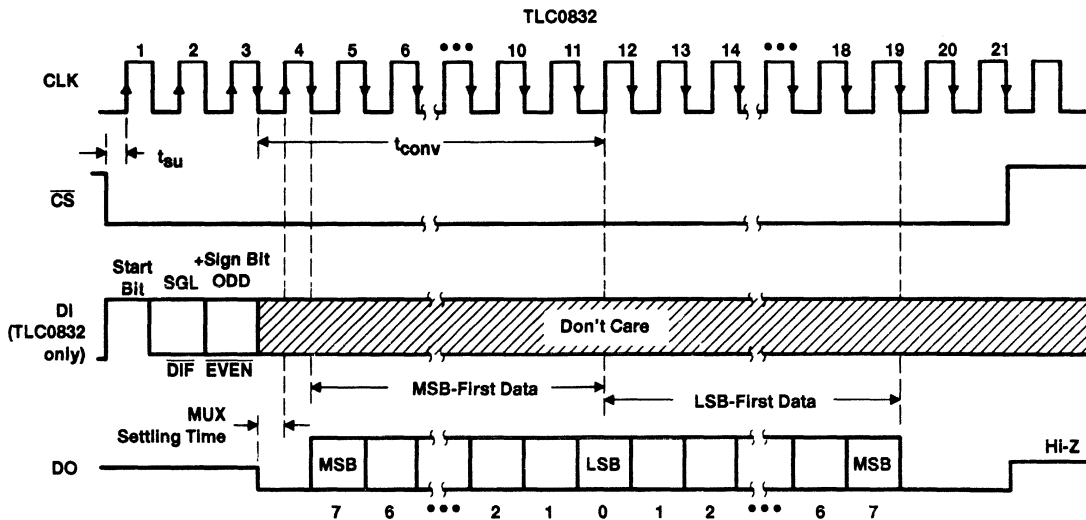
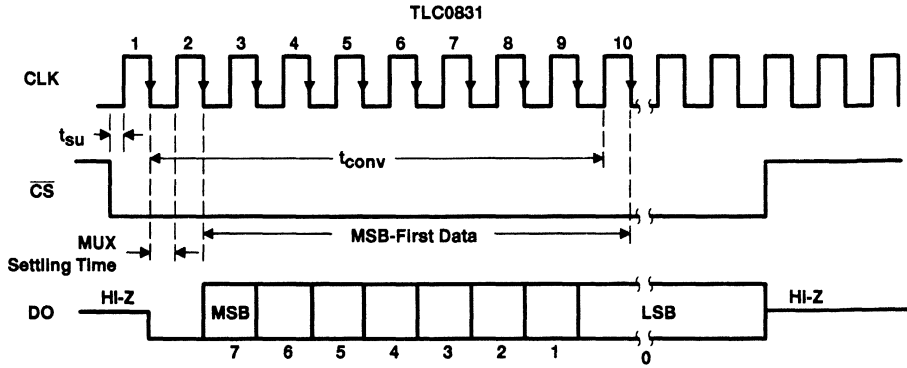
PRODUCT PREVIEW



TLC0831AC, TLC0831AI, TLC0831BC, TLC0831BI
 TLC0832AC, TLC0832AI, TLC0832BC, TLC0832BI
 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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sequence of operation



TLC0832 MUX-ADDRESS CONTROL LOGIC TABLE

MUX ADDRESS		CHANNEL NUMBER	
SGL/DIF	ODD/EVEN	0	1
L	L	+	-
L	H	-	+
H	L	+	2
H	H		+

H = high level, L = low level,
 - or + = polarity of selected input

PRODUCT PREVIEW



TLC0831AC, TLC0831AI, TLC0831BC, TLC0831BI
TLC0832AC, TLC0832AI, TLC0832BC, TLC0832BI
8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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electrical characteristics over recommended range of operating free-air temperature, $V_{CC} = 5\text{ V}$, $f_{clock} = 1\text{ MHz}$ (unless otherwise noted)

digital section

PARAMETER	TEST CONDITION [†]	C SUFFIX			I SUFFIX			UNIT
		MIN	TYP [‡]	MAX	MIN	TYP [‡]	MAX	
V _{OH} High-level output voltage	V _{CC} = 4.75 V, I _{OH} = -360 μA	2.8			2.4			V
	V _{CC} = 4.75 V, I _{OH} = -10 μA	4.6			4.5			
V _{OL} Low-level output voltage	V _{CC} = 4.75 V, I _{OL} = 1.6 mA	0.34			0.4			V
I _{IH} High-level input current	V _{IH} = 5 V		0.005	1		0.005	1	μA
I _{IL} Low-level input current	V _{IL} = 0		-0.005	-1		-0.005	-1	μA
I _{OH} High-level output (source) current	V _{OH} = V _O , T _A = 25°C	-6.5	-14		-6.5	-14		mA
I _{OL} Low-level output (sink) current	V _{OL} = V _{CC} , T _A = 25°C	8	16		8	16		mA
I _{OZ} High-impedance-state output current (DO)	V _O = 5 V, T _A = 25°C		0.01	3		0.01	3	μA
	V _O = 0, T _A = 25°C		-0.01	-3		-0.01	-3	
C _i Input capacitance			5		5			pF
C _o Output capacitance			5		5			pF

[†] All parameters are measured under open-loop conditions with zero common-mode input voltage.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

analog and converter section

PARAMETER	TEST CONDITION [†]	MIN	TYP [‡]	MAX	UNIT
V _{ICR} Common-mode input voltage	See Note 3	-0.05 to V _{CC} +0.05			V
I _{I(stdby)} Standby-input current (see Note 4)	On channel	V _I = 5 V		1	μA
	Off channel	V _I = 0		-1	
	On channel	V _I = 0		-1	
	Off channel	V _I = 5 V		1	
r _{i(REF)} Input resistance to REF		1.3	2.4	5.9	kΩ

[†] All parameters are measured under open-loop conditions with zero common-mode input voltage.

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

NOTES: 3. If channel IN₋ is more positive than channel IN₊, the digital output code will be 0000 0000. Connected to each analog input are two on-chip diodes that conduct forward current for analog input voltages one diode drop above V_{CC}. Care must be taken during testing at low V_{CC} levels (4.5 V) because high-level analog input voltage (5 V) can, especially at high temperatures, cause this input diode to conduct and cause errors for analog inputs that are near full scale. As long as the analog voltage does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0 to 5-V input voltage range requires a minimum V_{CC} of 4.95 V for all variations of temperature and load.

4. Standby-input currents are currents going into or out of the on or off channels when the A/D converter is not performing conversion and the clock is in a high or low steady-state conditions.

total device

PARAMETER	MIN	TYP [‡]	MAX	UNIT
I _{CC} Supply current	TLC0831	1	2.5	mA
	TLC0832	3	5.2	

[‡] All typical values are at V_{CC} = 5 V, T_A = 25°C.

PRODUCT PREVIEW



TLC0831AC, TLC0831AI, TLC0831BC, TLC0831BI
TLC0832AC, TLC0832AI, TLC0832BC, TLC0832BI
8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL
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operating characteristics $V_{CC} = V_{ref} = 5\text{ V}$, $f_{clock} = 1\text{ MHz}$, $t_r = t_f = 20\text{ ns}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†	AI, AC SUFFIX			BI, BC SUFFIX			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
Supply-voltage variation error		$V_{CC} = 4.75\text{ V to } 5.25\text{ V}$		$\pm 1/16$	$\pm 1/4$		$\pm 1/16$	$\pm 1/4$	LSB
Total unadjusted error (see Note 5)		$V_{ref} = 5\text{ V}$, $T_A = \text{MIN to MAX}$			± 1			$\pm 1/2$	LSB
Common-mode error		Differential mode		$\pm 1/16$	$\pm 1/4$		$\pm 1/16$	$\pm 1/4$	LSB
t_{pd}	Propagation delay time, output data after $\text{CLK}\uparrow$ (see Note 6)	MSB-first data	$C_L = 100\text{ pF}$	650	1500	650	1500	ns	
		LSB-first data		250	600	250	600		
t_{dis}	Output disable time, DO after $\overline{\text{CS}}\uparrow$	$C_L = 10\text{ pF}$, $R_L = 10\text{ k}\Omega$	125	250	125	250	ns		
		$C_L = 100\text{ pF}$, $R_L = 2\text{ k}\Omega$		500		500			
t_{conv}	Conversion time (multiplexer-addressing time not included)			8		8	clock periods		

† All parameters are measured under open-loop conditions with zero common-mode input voltage. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Total unadjusted error includes offset, full-scale, linearity, and multiplexer errors.

6. The MSB-first data is output directly from the comparator and therefore requires additional delay to allow for comparator response time. LBS-first data applies only to TLC0832.

PRODUCT PREVIEW



PARAMETER MEASUREMENT INFORMATION

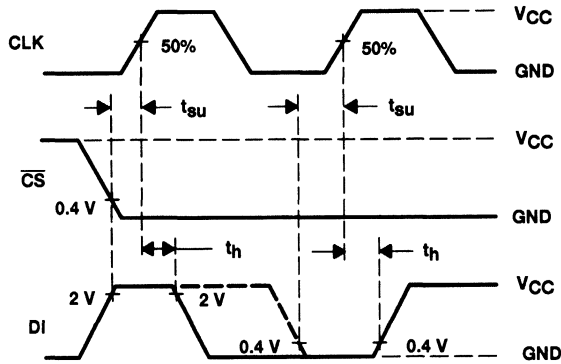


Figure 1. TLC0832 Data-Input Timing

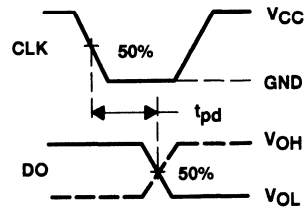
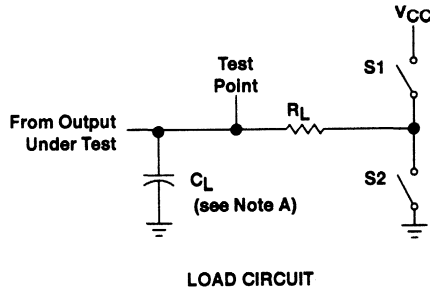
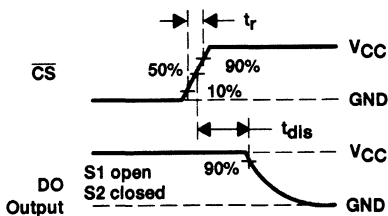


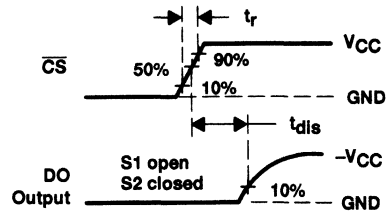
Figure 2. Data-Output Timing



LOAD CIRCUIT



VOLTAGE WAVEFORMS



VOLTAGE WAVEFORMS

NOTE A: C_L includes probe and jig capacitance.

Figure 3. Output Disable Time Test Circuit and Voltage Waveforms

PRODUCT PREVIEW

TYPICAL CHARACTERISTICS

PRODUCT PREVIEW

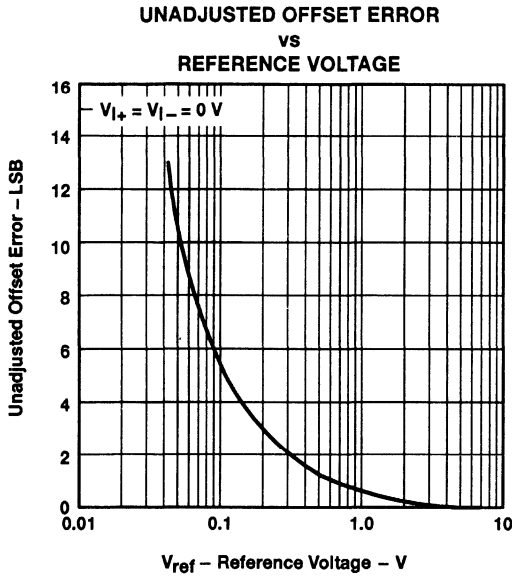


Figure 4

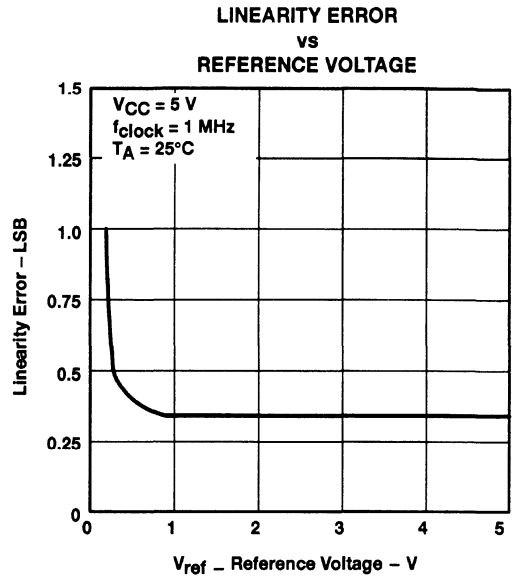


Figure 5

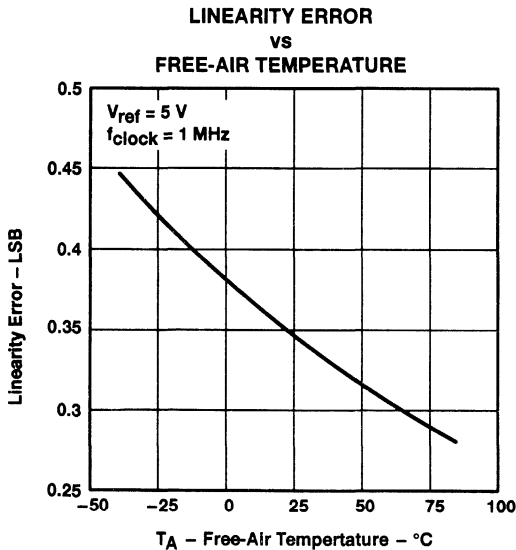


Figure 6

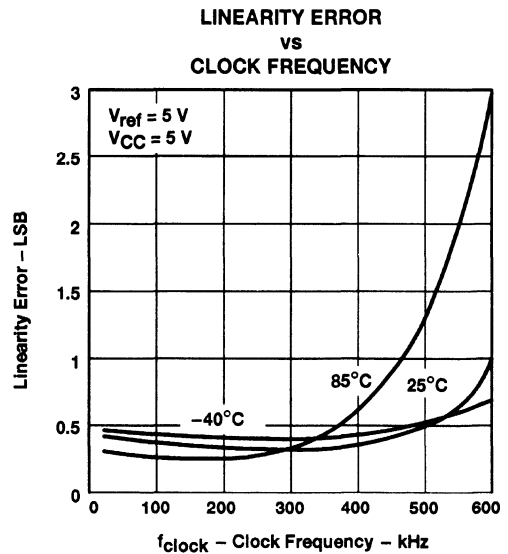


Figure 7

TLC0831AC, TLC0831AI, TLC0831BC, TLC0831BI
 TLC0832AC, TLC0832AI, TLC0832BC, TLC0832BI
 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL
 SLAS107 - JANUARY 1995

TYPICAL CHARACTERISTICS

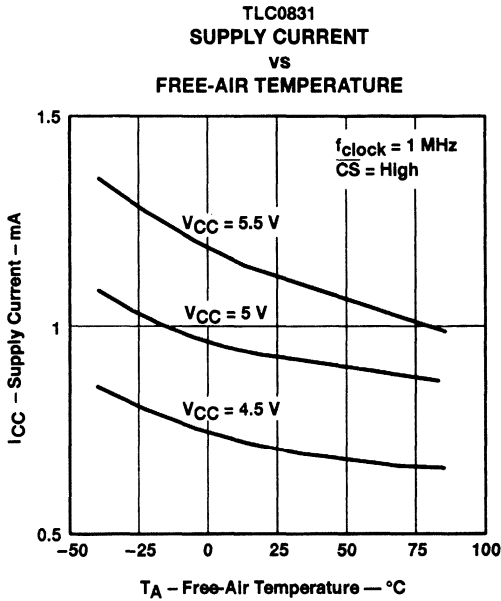


Figure 8

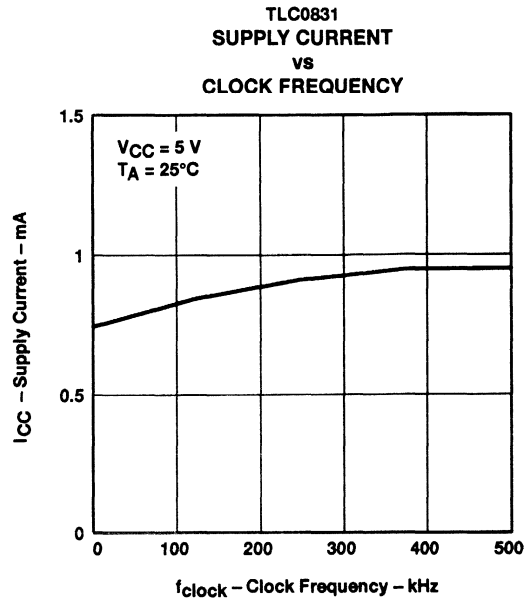


Figure 9

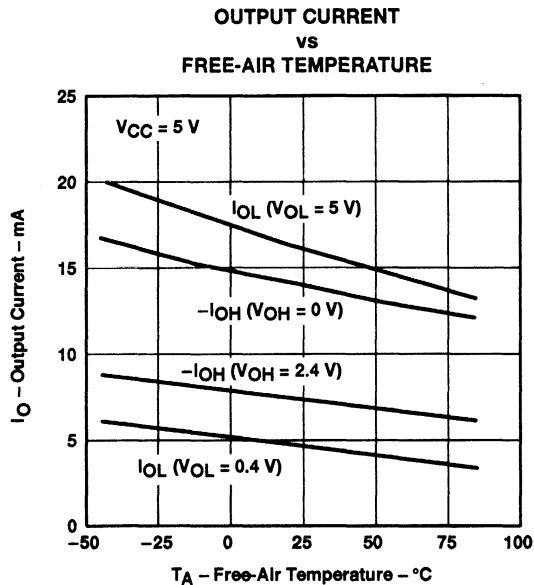


Figure 10

PRODUCT PREVIEW

TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI TLC0838AC, TLC0838AI, TLC0838BC, TLC0838BI 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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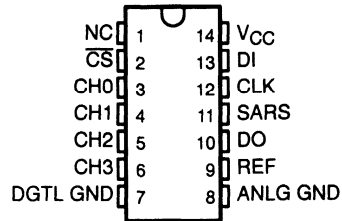
- 8-Bit Resolution
- Easy Microprocessor Interface or Stand-Alone Operation
- Operates Ratiometrically or With 5-V Reference
- 4- or 8-Channel Multiplexer Options With Address Logic
- Input Range 0 to 5 V With Single 5-V Supply
- Remote Operation With Serial Data Link
- Inputs and Outputs Are Compatible With TTL and MOS
- Conversion Time of 32 μ s at $f_{CLK} = 250$ kHz
- Functionally Equivalent to the ADC0834 and ADC0838 Without the Internal Zener Regulator Network

DEVICE	TOTAL UNADJUSTED ERROR	
	A-SUFFIX	B-SUFFIX
TLC0834	± 1 LSB	$\pm 1/2$ LSB
TLC0838	± 1 LSB	$\pm 1/2$ LSB

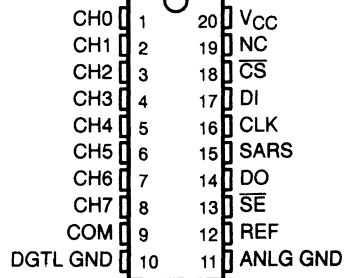
description

These devices are 8-bit successive-approximation analog-to-digital converters, each with an input-configurable multichannel multiplexer and serial input/output. The serial input/output is configured to interface with standard shift registers or microprocessors. Detailed information on interfacing with most popular microprocessors is readily available from the factory.

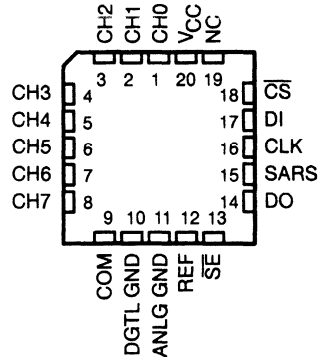
TLC0834 ... D OR N PACKAGE
(TOP VIEW)



TLC0838 ... DW OR N PACKAGE
(TOP VIEW)



TLC0838 ... FN PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE				
	SMALL OUTLINE (D)	SMALL OUTLINE (DW)	PLASTIC DIP (N)	CHIP CARRIER (FN)	
0°C to 70°C	TLC0834ACD TLC0834BCD	TLC0838ACDW TLC0838BCDW	TLC0834ACN TLC0834BCN	TLC0838ACN TLC0838BCN	TLC0838ACFN TLC0838BCFN
-40°C to 85°C	TLC0834AID TLC0834BID	TLC0838AIDW TLC0838BIDW	TLC0834AIN TLC0834BIN	TLC0838AIN TLC0838BIN	TLC0838AIFN TLC0838BIFN

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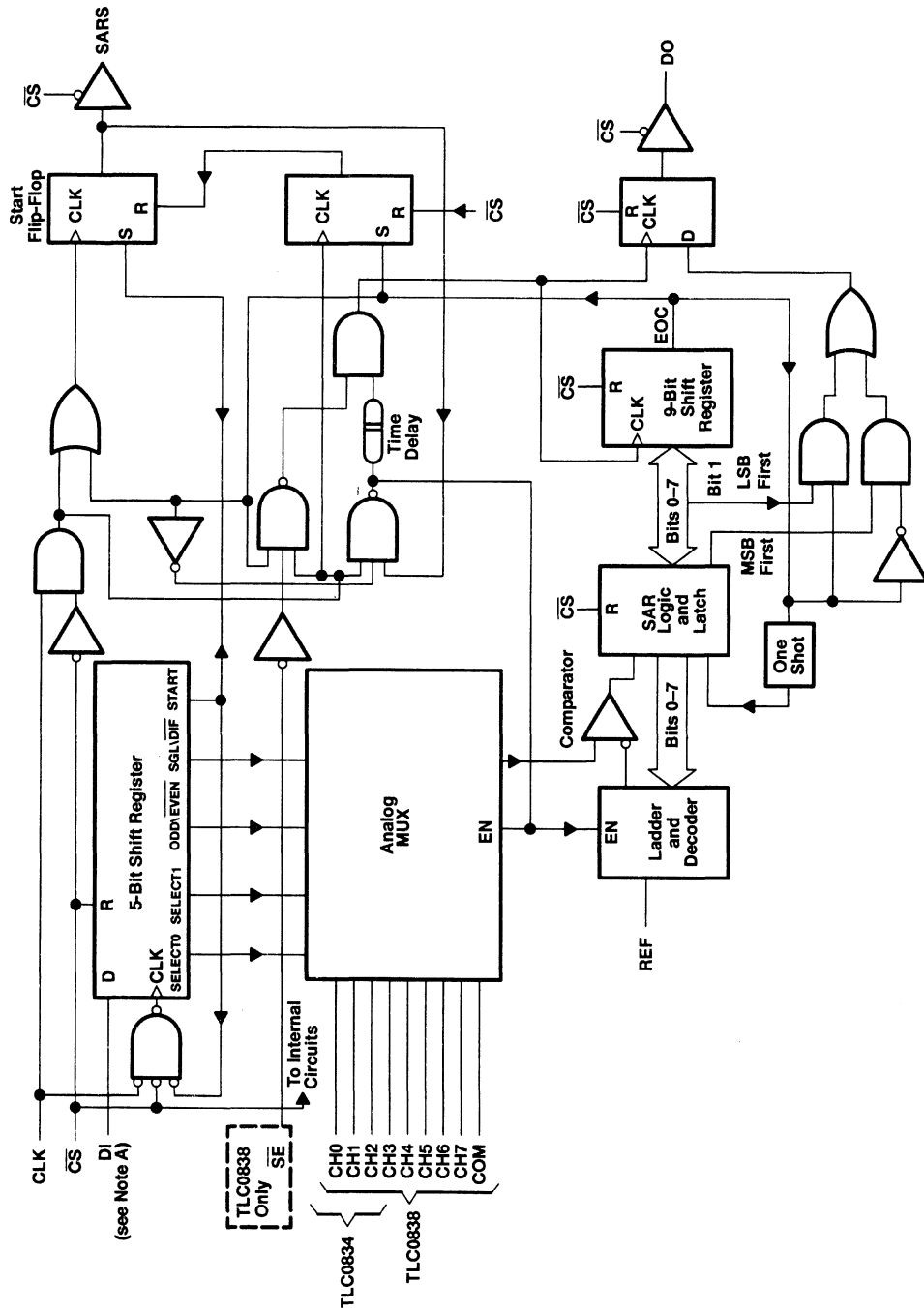
PRODUCT PREVIEW

TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI
 TLC0838AC, TLC0838AI, TLC0838BC, TLC0838BI
 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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PRODUCT PREVIEW

functional block diagram



NOTE A: For the TLC0834, DI is input directly to the D input of SELECT1; SELECT0 is forced to a high.

TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI TLC0838AC, TLC0838AI, TLC0838BC, TLC0838BI 8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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description (continued)

The TLC0834 (4-channel) and TLC0838 (8-channel) multiplexer is software configured for single-ended or differential inputs as well as pseudo-differential input assignments. The differential analog voltage input allows for common-mode rejection or offset of the analog zero input voltage value. In addition, the voltage reference input can be adjusted to allow encoding any smaller analog voltage span to the full 8 bits of resolution.

The TLC0834AC, TLC0834BC and TLC0838AC, TLC0838BC are characterized for operation from 0°C to 70°C. The TLC0834AI, TLC0834BI, and TLC0838AI, TLC0838BI are characterized for operation from –40°C to 85°C.

functional description

The TLC0834 and TLC0838 use a sample-data-comparator structure that converts differential analog inputs by a successive-approximation routine. Operation of both devices is similar with the exception of \overline{SE} , an analog common input, and multiplexer addressing. The input voltage to be converted is applied to a channel terminal and is compared to ground (single ended), to an adjacent input (differential), or to a common terminal (pseudo differential) that can be an arbitrary voltage. The input terminals are assigned a positive (+) or negative (–) polarity. If the signal input applied to the assigned positive terminal is less than the signal on the negative terminal, the converter output is all zeros.

Channel selection and input configuration are under software control using a serial-data link from the controlling processor. A serial-communication format allows more functions to be included in a converter package with no increase in size. In addition, it eliminates the transmission of low-level analog signals by locating the converter at the analog sensor and communicating serially with the controlling processor. This process returns noise-free digital data to the processor.

A particular input configuration is assigned during the multiplexer-addressing sequence. The multiplexer address is shifted into the converter through the data input (DI) line. The multiplexer address selects the analog inputs to be enabled and determines whether the input is single ended or differential. When the input is differential, the polarity of the channel input is assigned. Differential inputs are assigned to adjacent channel pairs. For example, channel 0 and channel 1 may be selected as a differential pair. These channels cannot act differentially with any other channel. In addition to selecting the differential mode, the polarity may also be selected. Either channel of the channel pair may be designated as the negative or positive input.

The common input on the TLC0838 can be used for a pseudo-differential input. In this mode, the voltage on the common input is considered to be the negative differential input for all channel inputs. This voltage can be any reference potential common to all channel inputs. Each channel input can then be selected as the positive differential input. This feature is useful when all analog circuits are biased to a potential other than ground.

A conversion is initiated by setting \overline{CS} low, which enables all logic circuits. \overline{CS} must be held low for the complete conversion process. A clock input is then received from the processor. On each low-to-high transition of the clock input, the data on DI is clocked into the multiplexer-address shift register. The first logic high on the input is the start bit. A 3- to 4-bit assignment word follows the start bit. On each successive low-to-high transition of the clock input, the start bit and assignment word are shifted through the shift register. When the start bit is shifted into the start location of the multiplexer register, the input channel is selected and conversion starts. The SAR status output (SARS) goes high to indicate that a conversion is in progress, and DI to the multiplexer shift register is disabled the duration of the conversion.

An interval of one clock period is automatically inserted to allow the selected multiplexed channel to settle. DO comes out of the high-impedance state and provides a leading low for this one clock period of multiplexer settling time. The SAR comparator compares successive outputs from the resistive ladder with the incoming analog signal. The comparator output indicates whether the analog input is greater than or less than the resistive-ladder output. As the conversion proceeds, conversion data is simultaneously output from DO, with the most significant bit (MSB) first. After eight clock periods, the conversion is complete and SARS goes low.

PRODUCT PREVIEW



TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI
TLC0838AC, TLC0838AI, TLC0838BC, TLC0838BI
8-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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functional description (continued)

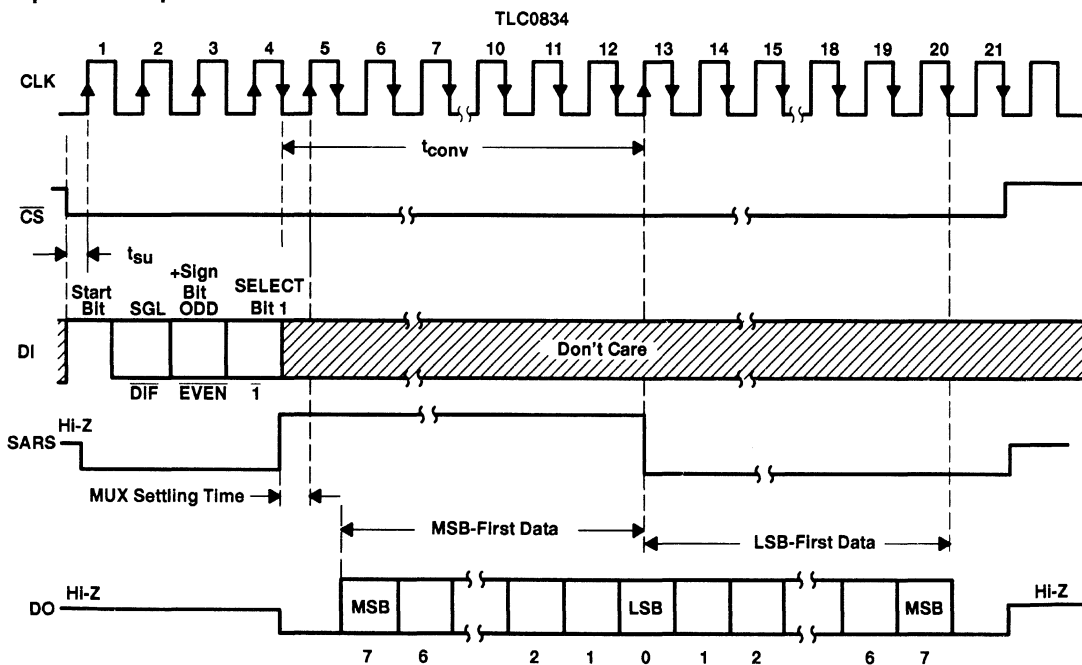
The TLC0834 outputs the least-significant-bit (LSB) first data after the MSB-first data stream. If \overline{SE} is held high on the TLC0838, the value of the LSB remains on the data line. When \overline{SE} is forced low, the data is then clocked out as LSB-first data. (To output LSB first, \overline{SE} must first go low, then the data stored in the 9-bit shift register outputs LSB first.) When \overline{CS} goes high, all internal registers are cleared. At this time, the output circuits go to the high-impedance state. If another conversion is desired, \overline{CS} must make a high-to-low transition followed by address information.

DI and DO can be tied together and controlled by a bidirectional processor I/O bit received on a single wire. This is possible because DI is only examined during the multiplexer-addressing interval and DO is still in the high-impedance state.

Detailed information on interfacing to most popular microprocessors is readily available from the factory.

sequence of operation

PRODUCT PREVIEW



TLC0834 MUX-ADDRESS CONTROL LOGIC TABLE

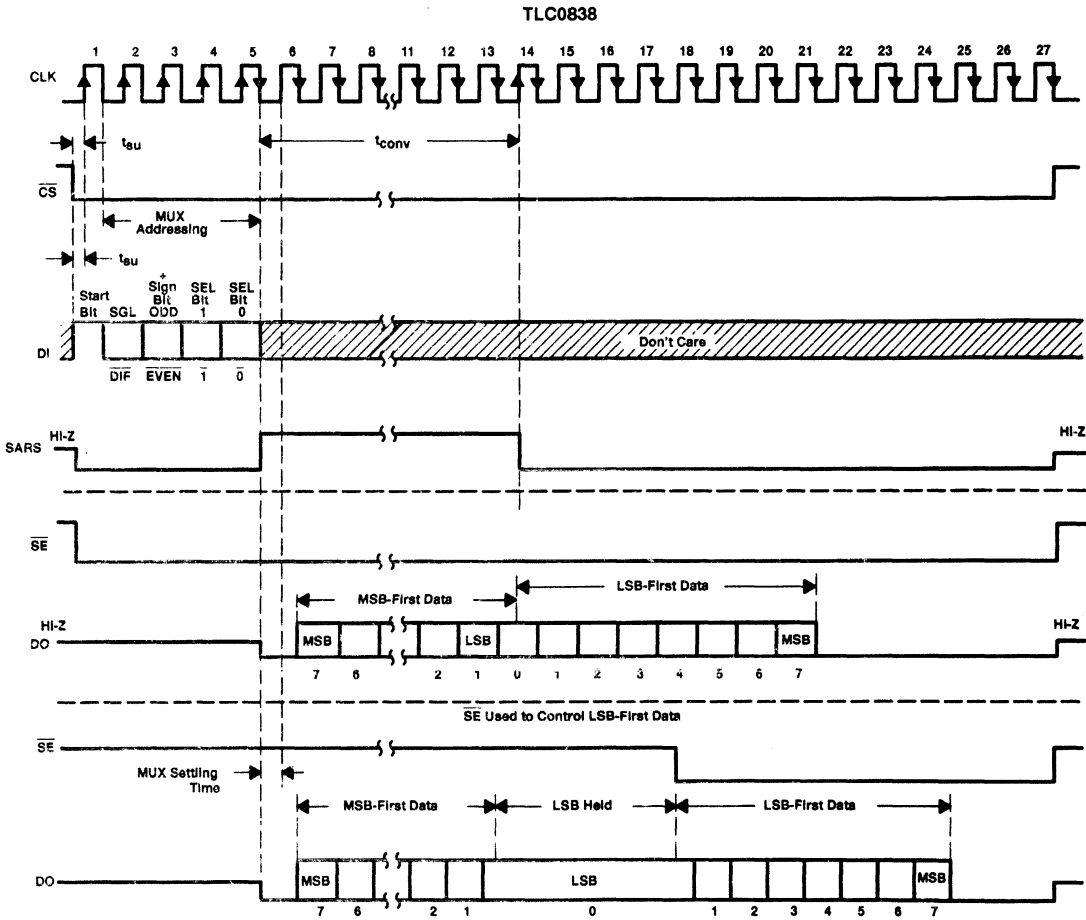
MUX ADDRESS			CHANNEL NUMBER			
SGL/DIF	ODD/EVEN	SELECT BIT 1	0	1	2	3
L	L	L	+	-		
L	L	H			+	-
L	H	L	-	+		
L	H	H			-	+
H	L	L	+			
H	L	H			+	
H	H	L		+		
H	H	H				+

H = high level, L = low level, - or + = polarity of selected input



TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI
 TLC0838AC, TLC0838AI, TLC0838BC, TLC0838BI
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sequence of operation



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TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI
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TLC0838 MUX-ADDRESS CONTROL LOGIC TABLE

MUX ADDRESS			SELECTED CHANNEL NUMBER							COM	
SGL/DIF	ODD/EVEN	SELECT	0		1		2		3		
		1 0	0 1	2 3	4 5	6 7					
L	L	L L	+	-							
L	L	L H			+	-					
L	L	H L					+	-			
L	L	H H							+	-	
L	H	L L	-	+							
L	H	L H			-	+					
L	H	H L					-	+			
L	H	H H							-	+	
H	L	L L	+								-
H	L	L H			+						-
H	L	H L					+				-
H	L	H H						+			-
H	H	L L		+							-
H	H	L H				+					-
H	H	H L						+			-
H	H	H H							+		-

H = high level, L = low level, - or + = polarity of selected input

PRODUCT PREVIEW

absolute maximum ratings over recommended operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	6.5 V
Input voltage range: Logic	-0.3 V to $V_{CC} + 0.3$ V
Analog	-0.3 V to $V_{CC} + 0.3$ V
Input current, I_I	± 5 mA
Total input current	± 20 mA
Operating free-air temperature range, T_A : C suffix	0°C to 70°C
I suffix	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds, T_C : FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values, except differential voltages, are with respect to the network ground terminal.



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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	6.3	V
High-level input voltage, V_{IH}		2			V
Low-level input voltage, V_{IL}				0.8	V
Clock frequency, f_{clock}		10		600	kHz
Clock duty cycle (see Note 2)		40%		60%	
Pulse duration, \overline{CS} high, $t_{WH}(\overline{CS})$		220			ns
Setup time, t_{SU}	\overline{CS} low, \overline{SE} low, or data valid before clock \uparrow	350			ns
Hold time, data valid after clock \uparrow , t_H		90			ns
Operating free-air temperature, T_A	C suffix	0		70	°C
	I suffix	-40		85	

NOTE 2: The clock-duty-cycle range ensures proper operation at all clock frequencies. If a clock frequency is used outside the recommended duty-cycle range, the minimum pulse duration (high or low) is 1 μ s.

electrical characteristics over recommended range of operating free-air temperature, $V_{CC} = 5$ V, $f_{clock} = 250$ kHz (unless otherwise noted)

digital section

PARAMETER	TEST CONDITIONS†	C SUFFIX			I SUFFIX			UNIT
		MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{OH} High-level output voltage	$V_{CC} = 4.75$ V, $I_{OH} = -360$ μ A	2.8			2.4			V
	$V_{CC} = 4.75$ V, $I_{OH} = -10$ μ A	4.6			4.5			
V_{OL} Low-level output voltage	$V_{CC} = 5.25$ V, $I_{OH} = 1.6$ mA			0.34			0.4	V
I_{IH} High-level input current	$V_{IH} = 5$ V		0.005	1		0.005	1	μ A
I_{IL} Low-level input current	$V_{IL} = 0$		-0.005	-1		-0.005	-1	μ A
I_{OH} High-level output (source) current	$V_{OH} = 0$, $T_A = 25^\circ$ C	-6.5	-14		-6.5	-14		mA
I_{OL} Low-level output (sink) current	$V_{OL} = V_{CC}$, $T_A = 25^\circ$ C	8	16		8	16		mA
I_{OZ} High-impedance-state output current (DO or SARS)	$V_O = 5$ V, $T_A = 25^\circ$ C		0.01	3		0.01	3	μ A
	$V_O = 0$, $T_A = 25^\circ$ C		-0.01	-3		-0.01	-3	
C_i Input capacitance						5		pF
C_o Output capacitance						5		pF

† All parameters are measured under open-loop conditions with zero common-mode input voltage (unless otherwise specified).

‡ All typical values are at $V_{CC} = 5$ V, $T_A = 25^\circ$ C.

PRODUCT PREVIEW



**TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI
TLC0838AC, TLC0838AI, TLC0838BC, TLC0838BI
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analog and converter section

PARAMETER		TEST CONDITIONS†	MIN	TYP‡	MAX	UNIT
V _{ICR}	Common-mode input voltage	See Note 3	-0.05 to V _{CC} +0.05			V
I _{I(stdby)}	Standby-input current (see Note 4)	On channel	V _I = 5 V		1	μA
		Off channel	V _I = 0		-1	
		On channel	V _I = 0		-1	
		Off channel	V _I = 5 V		1	
r _{i(REF)}	Input resistance to REF		1.3	2.4	5.9	kΩ

total device

PARAMETER		MIN	TYP‡	MAX	UNIT
I _{CC}	Supply current		1	2.5	mA

† All parameters are measured under open-loop conditions with zero common-mode input voltage.

‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.

- NOTES: 3. If channel IN₋ is more positive than channel IN₊, the digital output code will be 0000 0000. Connected to each analog input are two on-chip diodes that conduct forward current for analog input voltages one diode drop above V_{CC}. Care must be taken during testing at low V_{CC} levels (4.5 V) because high-level analog input voltage (5 V) can, especially at high temperatures, cause this input diode to conduct and cause errors for analog inputs that are near full scale. As long as the analog voltage does not exceed the supply voltage by more than 50 mV, the output code will be correct. To achieve an absolute 0 to 5-V input voltage range requires a minimum V_{CC} of 4.950 V for all variations of temperature and load.
4. Standby-input currents are currents going into or out of the on or off channels when the A/D converter is not performing conversion and the clock is in a high or low steady-state condition.

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TLC0834AC, TLC0834AI, TLC0834BC, TLC0834BI
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operating characteristics, $V_{CC} = 5\text{ V}$, $f_{\text{clock}} = 250\text{ kHz}$, $t_r = t_f = 20\text{ ns}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITION†	AI, AC SUFFIX			BI, BC SUFFIX			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
Supply-voltage variation error		$V_{CC} = 4.75\text{ V to }5.25\text{ V}$	$\pm 1/16$	$\pm 1/4$		$\pm 1/16$	$\pm 1/4$	LSB	
Total unadjusted error (see Note 5)		$V_{\text{ref}} = 5\text{ V}$, $T_A = \text{MIN to MAX}$		± 1			$\pm 1/2$	LSB	
Common-mode error		Differential mode	$\pm 1/16$	$\pm 1/4$		$\pm 1/16$	$\pm 1/4$	LSB	
t_{pd}	Propagation delay time, output data after CLK↓ (see Note 6)	MSB-first data	$C_L = 100\text{ pF}$			1500			ns
		LSB-first data							
t_{dis}	Output disable time, DO or SARS after CS↑	$C_L = 10\text{ pF}$, $R_L = 10\text{ k}\Omega$	250			250			ns
		$C_L = 100\text{ pF}$, $R_L = 2\text{ k}\Omega$							
t_{conv}	Conversion time (multiplexer-addressing time not included)		8			8			clock periods

† All parameters are measured under open-loop conditions with zero common-mode input voltage. For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions.

NOTES: 5. Total unadjusted error includes offset, full-scale, linearity, and multiplexer errors.

6. The MSB-first data is output directly from the comparator and therefore requires additional delay to allow for comparator response time.

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PARAMETER MEASUREMENT INFORMATION

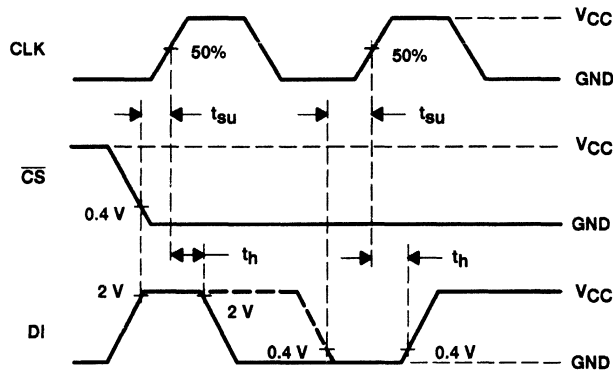


Figure 1. Data-Input Timing

PARAMETER MEASUREMENT INFORMATION

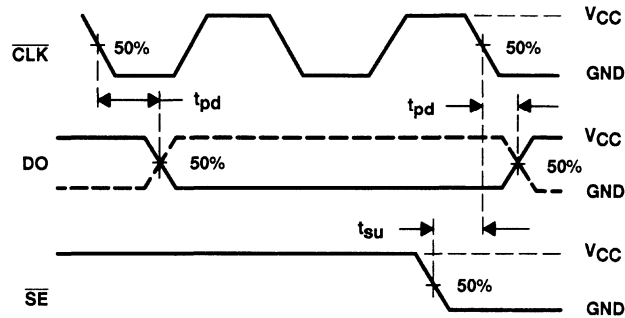
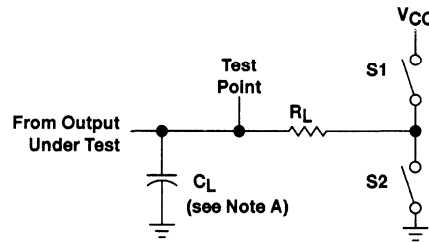
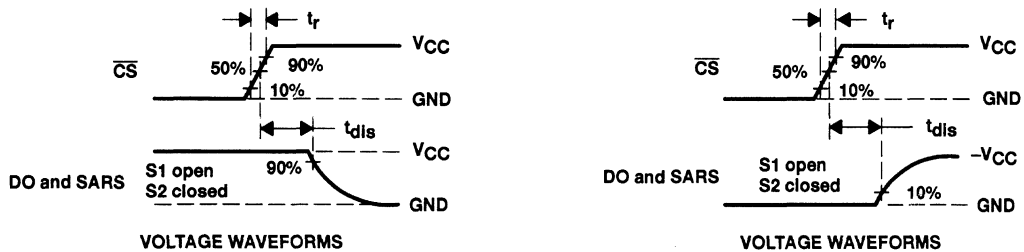


Figure 2. Data-Output Timing



LOAD CIRCUIT



VOLTAGE WAVEFORMS

VOLTAGE WAVEFORMS

NOTE A: C_L includes probe and jig capacitance.

Figure 3. Output Disable Time Test Circuit and Voltage Waveforms

PRODUCT PREVIEW

TYPICAL CHARACTERISTICS

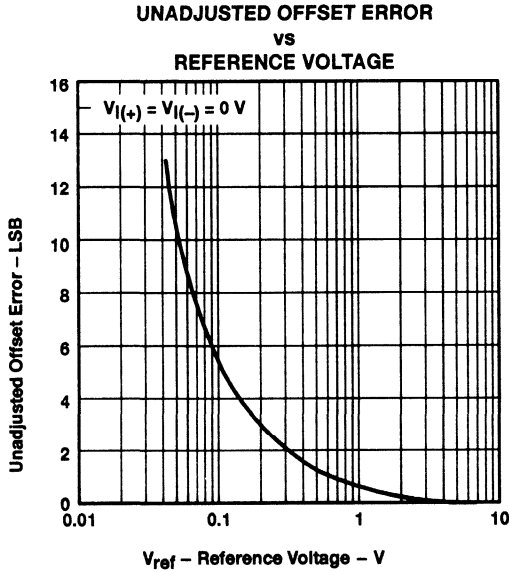


Figure 4

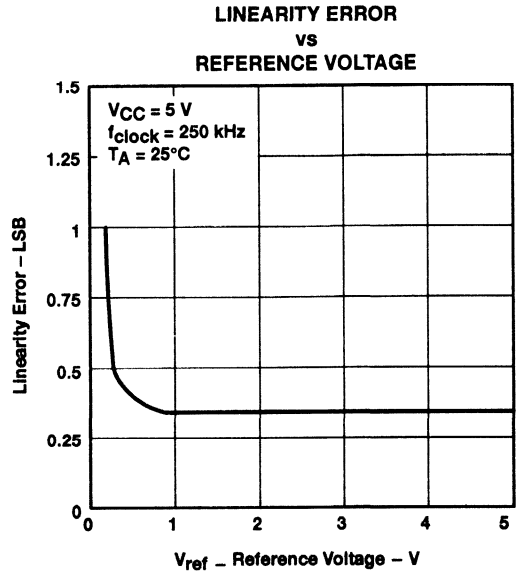


Figure 5

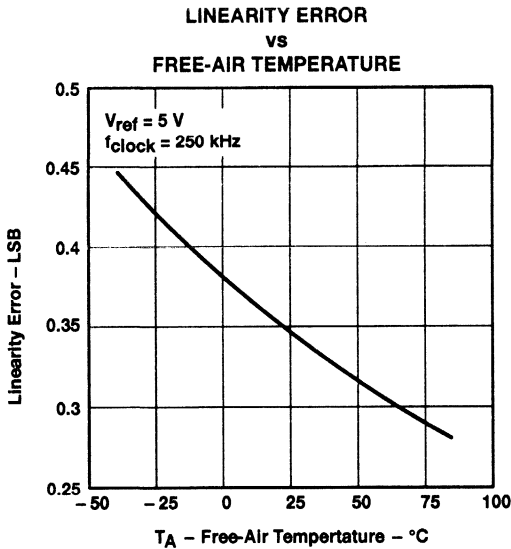


Figure 6

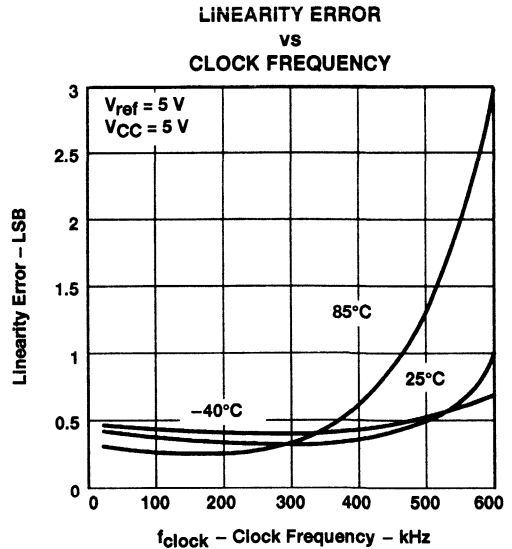


Figure 7

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TYPICAL CHARACTERISTICS

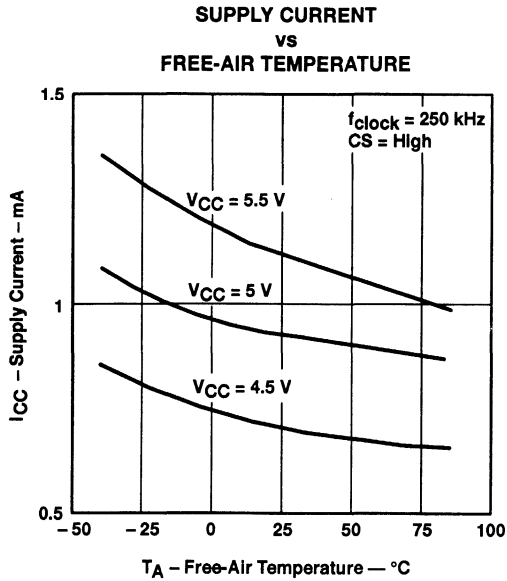


Figure 8

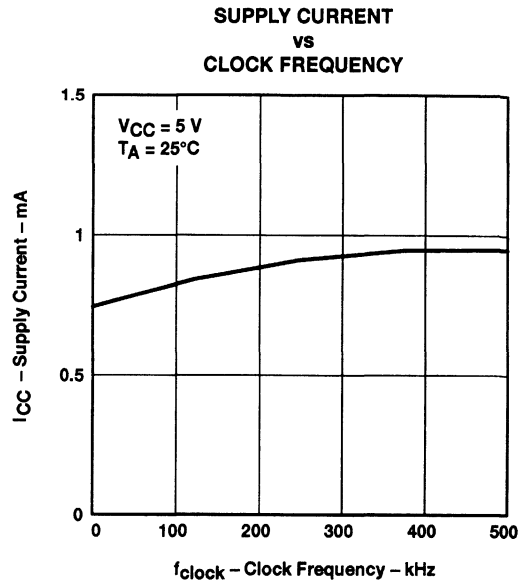


Figure 9

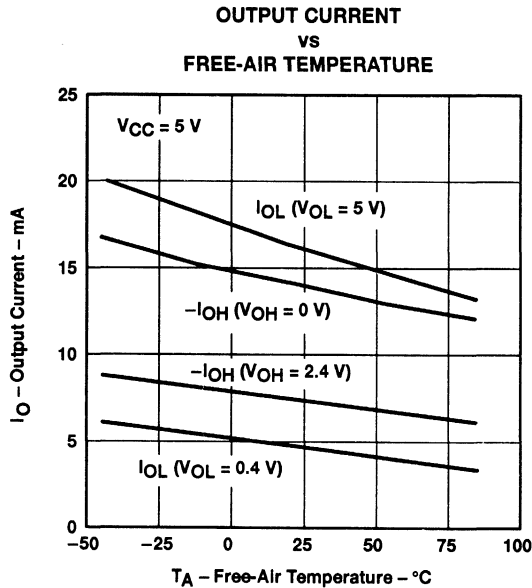


Figure 10

PRODUCT PREVIEW

TLC1540C, TLC1541C 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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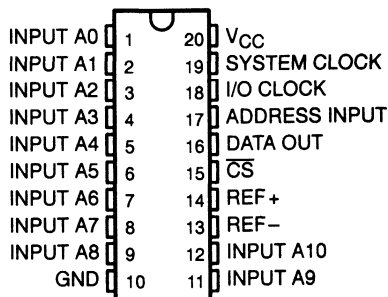
- 10-Bit Resolution A/D Converter
- Microprocessor Peripheral or Stand-Alone Operation
- On-Chip 12-Channel Analog Multiplexer
- Built-In Self-Test Mode
- Software-Controllable Sample and Hold
- Total Unadjusted Error
TLC1540: ± 0.5 LSB Max
TLC1541: ± 1 LSB Max
- Pinout and Control Signals Compatible With TLC540 and TLC549 Families of 8-Bit A/D Converters
- CMOS Technology

PARAMETER	VALUE
Channel Acquisition Sample Time	5.5 μ s
Conversion Time (Max)	21 μ s
Samples Per Second (Max)	32×10^3
Power Dissipation (Max)	6 mW

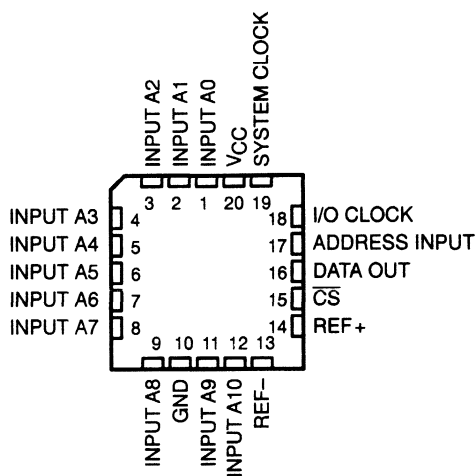
description

The TLC1540 and TLC1541 are CMOS A/D converters built around a 10-bit, switched-capacitor, successive-approximation A/D converter. They are designed for serial interface to a microprocessor or peripheral via a 3-state output with up to four control inputs [including independent SYSTEM CLOCK, I/O CLOCK, chip select (\overline{CS}), and ADDRESS INPUT]. A 2.1-MHz system clock for the TLC1540 and TLC1541, with a design that includes simultaneous read/write operation, allows high-speed data transfers and sample rates of up to 32,258 samples per second. In addition to the high-speed converter and versatile control logic, there is an on-chip, 12-channel analog multiplexer that can be used to sample any one of 11 inputs or an internal self-test voltage and a sample and hold that can operate automatically or under microprocessor control. Detailed information on interfacing to most popular microprocessors is readily available from the factory.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE		
	PLASTIC DIP (DW)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC1540CDW TLC1541CDW	TLC1540CFN TLC1541CFN	TLC1540CN TLC1541CN

TLC1540C, TLC1541C 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

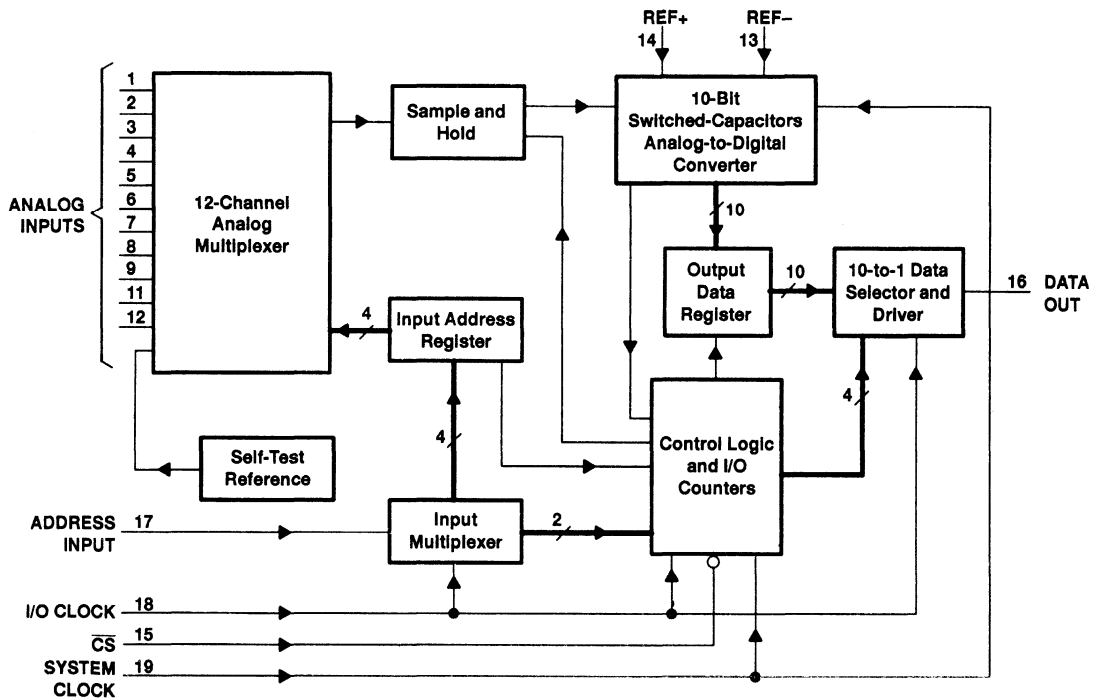
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description (continued)

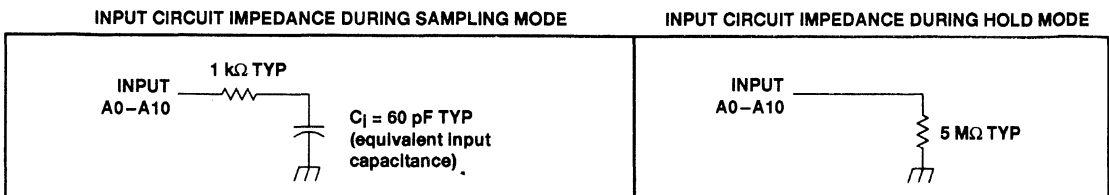
The converters incorporated in the TLC1540 and TLC1541 feature differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and analog circuitry isolation from logic and supply noises. A totally switched-capacitor design allows low-error conversion (± 0.5 LSB for the TLC1540, ± 1 LSB for the TLC1541) in 21 μ s over the full operating temperature range.

The TLC1540 and the TLC1541 are available in DW, FN, and N packages. The C-suffix versions are characterized for operation from 0°C to 70°C.

functional block diagram

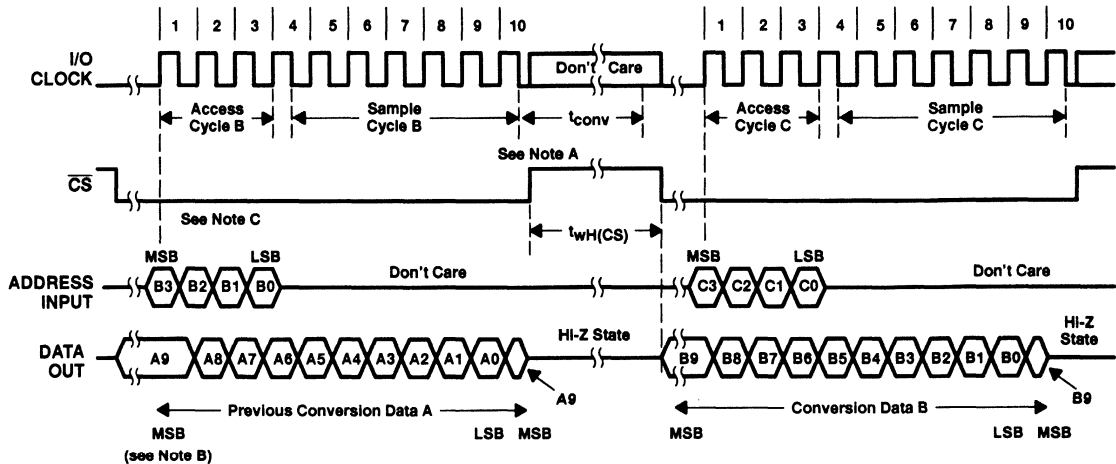


typical equivalent inputs



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operating sequence



- NOTES: A. The conversion cycle, which requires 44 system clock periods, initiates on the tenth falling edge of the I/O clock after \overline{CS} goes low for the channel whose address exists in memory at that time. If \overline{CS} is kept low during conversion, the I/O clock must remain low for at least 44 system clock cycles to allow the conversion to complete.
- B. The most significant bit (MSB) is automatically placed on the DATA OUT bus after \overline{CS} is brought low. The remaining nine bits (A8–A0) clock out on the first nine I/O clock falling edges.
- C. To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for three system clock cycles (or less) after a chip-select falling edge is detected before responding to control input signals. Therefore, no attempt should be made to clock-in address data until the minimum chip-select setup time elapses.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	6.5 V
Input voltage range, V_I (any input)	–0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O	–0.3 V to $V_{CC} + 0.3$ V
Peak input current (any input)	±10 mA
Peak total input current (all inputs)	±30 mA
Operating free-air temperature range, T_A : TLC1540C, TLC1541C	0°C to 70°C
Storage temperature range, T_{stg}	–65°C to 150°C
Case temperature for 10 seconds, T_C : FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds: DW or N package	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to digital ground with REF– and GND wired together (unless otherwise noted).

TLC1540C, TLC1541C

10-BIT ANALOG-TO-DIGITAL CONVERTERS

WITH SERIAL CONTROL AND 11 INPUTS

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recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	4.75	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)	2.5	V_{CC}	$V_{CC}+0.1$	V
Negative reference voltage, V_{ref-} (see Note 2)	-0.1	0	2.5	V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)	1	V_{CC}	$V_{CC}+0.2$	V
Analog input voltage (see Note 2)	0		V_{CC}	V
High-level control input voltage, V_{IH}	2			V
Low-level control input voltage, V_{IL}			0.8	V
Input/output clock frequency, $f_{clock(I/O)}$	0		1.1	MHz
System clock frequency, $f_{clock(SYS)}$	$f_{clock(I/O)}$		2.1	MHz
Setup time, address bits before I/O CLOCK \uparrow , $t_{su(A)}$	400			ns
Hold time, address bits after I/O CLOCK \uparrow , $t_h(A)$	0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su(CS)}$ (see Note 3)	3			System clock cycles
Pulse duration, \overline{CS} high during conversion, $t_{wH(CS)}$	44			System clock cycles
Pulse duration, SYSTEM CLOCK high, $t_{wH(SYS)}$	210			ns
Pulse duration, SYSTEM CLOCK low, $t_{wL(SYS)}$	190			ns
Pulse duration, I/O CLOCK high, $t_{wH(I/O)}$	404			ns
Pulse duration, I/O CLOCK low, $t_{wL(I/O)}$	404			ns
Clock transition time (see Note 4)	System	$f_{clock(SYS)} \leq 1048$ kHz	30	ns
		$f_{clock(SYS)} > 1048$ kHz	20	
	I/O	$f_{clock(I/O)} \leq 525$ kHz	100	ns
		$f_{clock(I/O)} > 525$ kHz	40	
Operating free-air temperature, T_A	0		70	°C

- NOTES: 2. Analog input voltages greater than that applied to REF + convert as all ones (1111111111), while input voltages less than that applied to REF - convert as all zeros (0000000000). For proper operation, REF + voltage must be at least 1 V higher than REF - voltage. Also, the total unadjusted error may increase as this differential reference voltage falls below 4.75 V.
3. To minimize errors caused by noise at the chip select input, the internal circuitry waits for three system clock cycles (or less) after a chip select falling edge is detected before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum chip select setup time elapses.
4. The amount of time required for the clock input signal to fall from V_{IH} min to V_{IL} max or to rise from V_{IL} max to V_{IH} min. In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 2 μ s for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.



TLC1540C, TLC1541C
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electrical characteristics over recommended operating temperature range, $V_{CC} = V_{ref+} = 4.75$ V to 5.5 V (unless otherwise noted), $f_{clock(I/O)} = 1.1$ MHz, $f_{clock(SYS)} = 2.1$ MHz

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage (terminal 16)	$V_{CC} = 4.75$ V, $I_{OH} = 360$ μ A	2.4			V
V_{OL}	Low-level output voltage	$V_{CC} = 4.75$ V, $I_{OL} = 3.2$ mA			0.4	V
I_{OZ}	High-impedance-state output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}			10	μ A
		$V_O = 0$, \overline{CS} at V_{CC}			-10	
I_{IH}	High-level input current	$V_I = V_{CC}$		0.005	2.5	μ A
I_{IL}	Low-level input current	$V_I = 0$		-0.005	-2.5	μ A
I_{CC}	Operating supply current	\overline{CS} at 0 V		1.2	2.5	mA
	Selected channel leakage current	Selected channel at V_{CC} , Unselected channel at 0 V		0.4	1	μ A
		Selected channel at 0 V, Unselected channel at V_{CC}		-0.4	-1	
$I_{CC} + I_{ref}$	Supply and reference current	$V_{ref+} = V_{CC}$, \overline{CS} at 0 V		1.3	3	mA
C_i	Input capacitance	Analog inputs		7	55	pF
		Control inputs		5	15	

† All typical values are at $V_{CC} = 5$ V and $T_A = 25^\circ$ C.

TLC1540C, TLC1541C

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operating characteristics over recommended operating temperature range, $V_{CC} = V_{ref+} = 4.75\text{ V}$ to 5.5 V , $f_{clock(I/O)} = 1.1\text{ MHz}$, $f_{clock(SYS)} = 2.1\text{ MHz}$

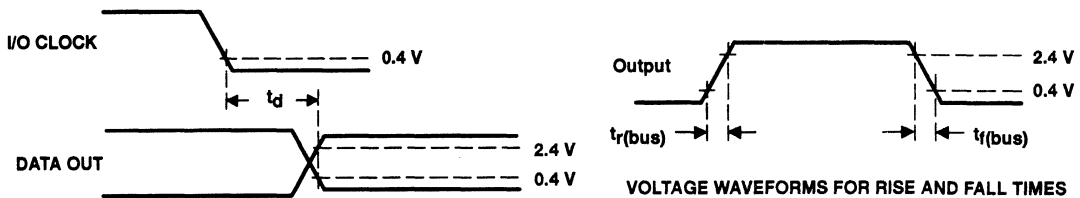
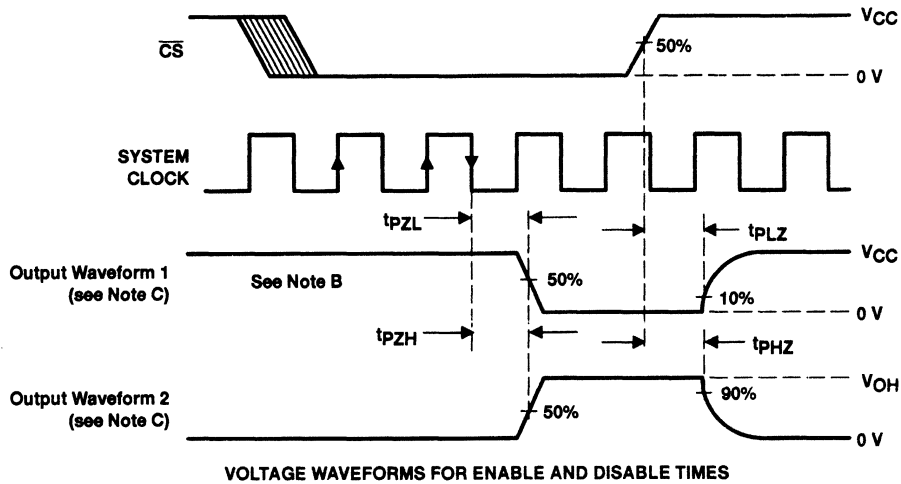
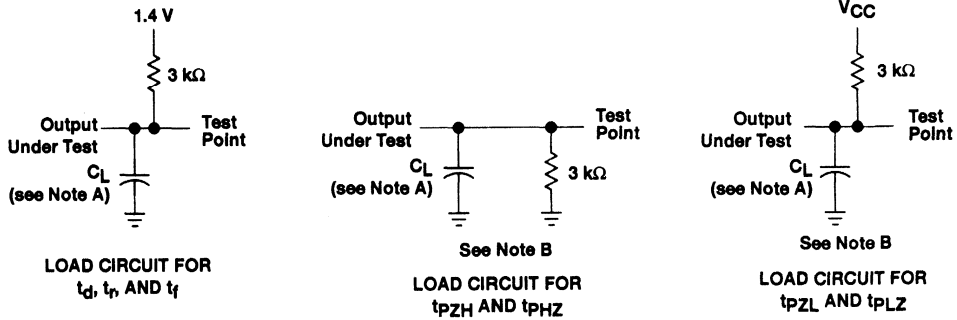
PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
E _L	Linearity error	TLC1540	See Note 5	±0.5	LSB
		TLC1541		±1	
E _{ZS}	Zero-scale error	TLC1540	See Notes 2 and 6	±0.5	LSB
		TLC1541		±1	
E _{FS}	Full-scale error	TLC1540	See Notes 2 and 6	±0.5	LSB
		TLC1541		±1	
E _T	Total unadjusted error	TLC1540	See Note 7	±0.5	LSB
		TLC1541		±1	
Self-test output code		Input A11 address = 1011 (see Note 8)	0111110100 (500)	1000001100 (524)	
t _{conv}	Conversion time	See Operating Sequence		21	μs
Total access and conversion time		See Operating Sequence		31	μs
t _{acq}	Channel acquisition time (sample cycle)	See Operating Sequence		6	I/O clock cycles
t _v	Time output data remains valid after I/O CLOCK↓		10		ns
t _d	Delay time, I/O CLOCK↓ to DATA OUT valid	See Parameter Measurement Information		400	ns
t _{en}	Output enable time			150	ns
t _{dis}	Output disable time			150	ns
t _{r(bus)}	Data bus rise time			300	ns
t _{f(bus)}	Data bus fall time			300	ns

- NOTES:
- Analog input voltages greater than that applied to REF+ convert as all ones (1111111111), while input voltages less than that applied to REF- convert as all zeros (0000000000). For proper operation, REF+ voltage must be at least 1 V higher than REF- voltage. Also, the total unadjusted error may increase as this differential reference voltage falls below 4.75 V.
 - Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
 - Zero-scale error is the difference between 0000000000 and the converted output for zero input voltage; full-scale error is the difference between 1111111111 and the converted output for full-scale input voltage.
 - Total unadjusted error includes linearity, zero-scale, and full-scale errors.
 - Both the input address and the output codes are expressed in positive logic. The A11 analog input signal is internally generated and used for test purposes.



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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. $C_L = 50 \text{ pF}$
 B. $t_{en} = t_{pZH}$ or t_{pZL} and $t_{dis} = t_{pHZ}$ or t_{pLZ} .
 C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.

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APPLICATION INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 1, the time required to charge the analog input capacitance from 0 V to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S (1 - e^{-t_c/R_t C_i}) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/2048) \quad (2)$$

Equating equation 1 to equation 2 and solving for time (t_c) gives

$$V_S - (V_S/2048) = V_S (1 - e^{-t_c/R_t C_i}) \quad (3)$$

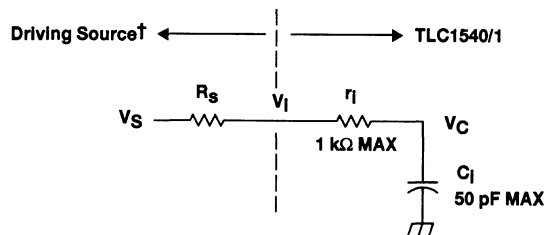
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(2048) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(2048) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at INPUT A0–A10
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 1. Equivalent Input Circuit Including the Driving Source

PRINCIPLES OF OPERATION

The TLC1540 and TLC1541 are complete data acquisition systems on single chips. Each includes such functions as sample and hold, 10-bit A/D converter, data and control registers, and control logic. For flexibility and access speed, there are four control inputs: chip select (\overline{CS}), address input, I/O clock, and system clock. These control inputs and a TTL-compatible, 3-state output are intended for serial communications with a microprocessor or microcomputer. The TLC1540 and TLC1541 can complete conversions in a maximum of 21 μ s, while complete input-conversion-output cycles can be repeated at a maximum of 31 μ s.

The system and I/O clocks are normally used independently and do not require any special speed or phase relationships between them. This independence simplifies the hardware and software control tasks for the device. Once a clock signal within the specification range is applied to the SYSTEM CLOCK input, the control hardware and software need only be concerned with addressing the desired analog channel, reading the previous conversion result, and starting the conversion by using I/O CLOCK. SYSTEM CLOCK will drive the conversion-crunching circuitry so that the control hardware and software need not be concerned with this task.

When \overline{CS} is high, DATA OUT is in a 3-state condition and ADDRESS INPUT and I/O CLOCK are disabled. This feature allows each of these terminals, with the exception of the \overline{CS} terminal, to share a control logic point with its counterpart terminals on additional A/D devices when using additional TLC1540/1541 devices. In this way, the above feature serves to minimize the required control logic terminals when using multiple A/D devices.

The control sequence has been designed to minimize the time and effort required to initiate conversion and obtain the conversion result. A normal control sequence is:

1. \overline{CS} is brought low. To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for two rising edges and then a falling edge of SYSTEM CLOCK after a low \overline{CS} transition before recognizing the low transition. This technique protects the device against noise when the device is used in a noisy environment. The MSB of the previous conversion result automatically appears on DATA OUT.
2. A new positive-logic multiplexer address shifts in on the first four rising edges of I/O CLOCK. The MSB of the address shifts in first. The negative edges of these four I/O clock pulses shift out the second, third, fourth, and fifth most-significant bits of the previous conversion result. The on-chip sample-and-hold begins sampling the newly addressed analog input after the fourth falling edge. The sampling operation basically involves the charging of internal capacitors to the level of the analog input voltage.
3. Five clock cycles are then applied to the I/O CLOCK, and the sixth, seventh, eighth, ninth, and tenth conversion bits shift out on the negative edges of these clock cycles.
4. The final tenth-clock cycle is applied to the I/O CLOCK. The falling edge of this clock cycle completes the analog sampling process and initiates the hold function. Conversion is then performed during the next 44 system clock cycles. After this final I/O clock cycle, \overline{CS} must go high or the I/O CLOCK must remain low for at least 44 system-clock cycles to allow for the conversion function.

\overline{CS} can be kept low during periods of multiple conversion. When keeping \overline{CS} low during periods of multiple conversion, special care must be exercised to prevent noise glitches on I/O CLOCK. If glitches occur on I/O CLOCK, the I/O sequence between the microprocessor/controller and the device loses synchronization. Also, if \overline{CS} goes high, it must remain high until the end of the conversion. Otherwise, a valid falling edge of \overline{CS} causes a reset condition, which aborts the conversion in progress.

A new conversion may be started and the ongoing conversion simultaneously aborted by performing steps 1 through 4 before the 44 system-clock cycles occur. Such action yields the conversion result of the previous conversion and not the ongoing conversion.

TLC1540C, TLC1541C 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 INPUTS

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PRINCIPLES OF OPERATION

It is possible to connect SYSTEM CLOCK and I/O CLOCK together in special situations in which controlling-circuitry points must be minimized. In this case, the following special points must be considered in addition to the requirements of the normal control sequence previously described.

1. This device requires the first two clocks to recognize that \overline{CS} is at a valid low level when the common clock signal is used as an I/O CLOCK. When \overline{CS} is recognized by the device to be at a high level, the common clock signal is used for the conversion clock also.
2. A low \overline{CS} must be recognized before the I/O CLOCK can shift in an analog channel address. The device recognizes a \overline{CS} transition when the SYSTEM CLOCK terminal receives two positive edges and then a negative edge. For this reason, after a \overline{CS} negative edge, the first two clock cycles do not shift in the address. Also, upon shifting in the address, \overline{CS} must be raised after the tenth valid (12 total) I/O CLOCK. Otherwise, additional common-clock cycles are recognized as I/O CLOCK cycles and shift in an erroneous address.

For certain applications, such as strobing applications, it is necessary to start conversion at a specific point in time. This device accommodates these applications. Although the on-chip sample-and-hold begins sampling upon the negative edge of the fourth valid I/O CLOCK cycle, the hold function does not initiate until the negative edge of the eighth valid I/O CLOCK cycle. Thus, the control circuitry can leave the I/O CLOCK signal in its high state during the tenth valid I/O CLOCK cycle until the moment at which the analog signal must be converted. The TLC1540/TLC1541 continues sampling the analog input until the eighth valid falling edge of the I/O CLOCK. The control circuitry or software then immediately lowers the I/O CLOCK signal and holds the analog signal at the desired point in time and starts the conversion.

Detailed information on interfacing to most popular microprocessors is readily available from the factory.



TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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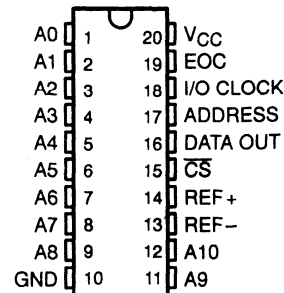
- 10-Bit-Resolution A/D Converter
- 11 Analog Input Channels
- Three Built-In Self-Test Modes
- Inherent Sample and Hold
- Total Unadjusted Error . . . ± 1 LSB Max
- On-Chip System Clock
- End-of-Conversion (EOC) Output
- Terminal Compatible With TLC1542
- CMOS Technology

description

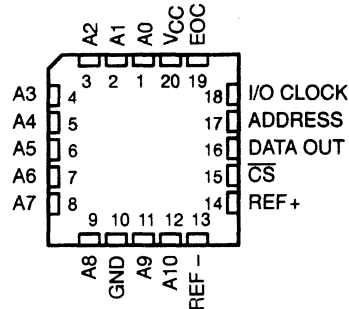
The TLC1543C, TLC1543I, and TLC1543Q are CMOS 10-bit, switched-capacitor, successive-approximation, analog-to-digital converters. These devices have three inputs and a 3-state output [chip select (\overline{CS}), input-output clock (I/O CLOCK), address input (ADDRESS), and data output (DATA OUT)] that provide a direct four-wire interface to the serial port of a host processor. These devices allow high-speed data transfers from the host.

In addition to a high-speed A/D converter and versatile control capability, these devices have an on-chip 14-channel multiplexer that can select any one of 11 analog inputs or any one of three internal self-test voltages. The sample-and-hold function is automatic. At the end of A/D conversion, the end-of-conversion (EOC) output goes high to indicate that conversion is complete. The converter incorporated in the devices features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating free-air temperature range.

DB, J, DW, OR N PACKAGE
(TOP VIEW)



FK OR FN PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE					
	SMALL OUTLINE (DB)	SMALL OUTLINE (DW)	CHIP CARRIER (FN)	PLASTIC DIP (N)	CHIP CARRIER (FK)	CERAMIC DIP (J)
0°C to 70°C		TLC1542CDW	TLC1542CFN	TLC1542CN		
	TLC1543CDB	TLC1543CDW	TLC1543CFN	TLC1543CN		
-40°C to 85°C		TLC1542IDW	TLC1542IFN	TLC1542IN		
		TLC1543IDW	TLC1543IFN	TLC1543IN		
-40°C to 125°C		TLC1542QDW	TLC1542QFN	TLC1542QN		
		TLC1543QDW	TLC1543QFN	TLC1543QN		
-55°C to 125°C					TLC1542MFK	TLC1542MJ

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



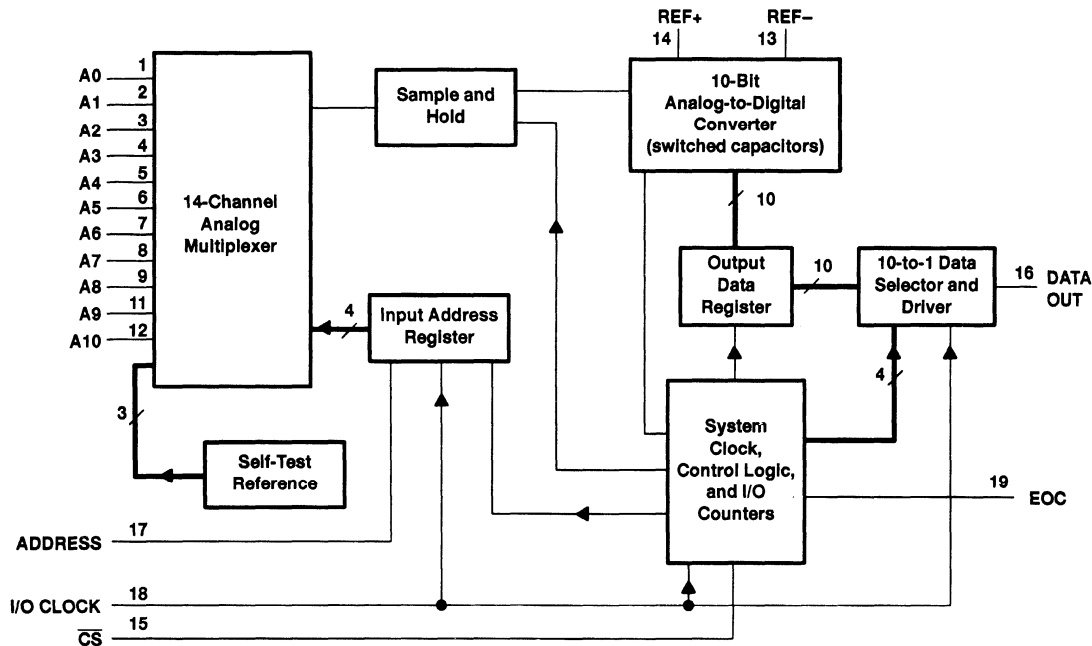
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TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

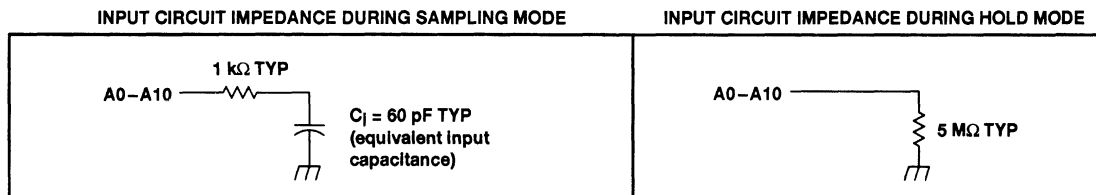
10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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functional block diagram



typical equivalent inputs



TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ADDRESS	17	I	Serial address input. A 4-bit serial address selects the desired analog input or test voltage that is to be converted next. The address data is presented with the MSB first and is shifted in on the first four rising edges of I/O CLOCK. After the four address bits have been read into the address register, this input is ignored for the remainder of the current conversion period.
A0–A10	1–9, 11, 12	I	Analog signal inputs. The 11 analog inputs are applied to these terminals and are internally multiplexed. The driving source impedance should be less than or equal to 1 k Ω .
\overline{CS}	15	I	Chip select. A high-to-low transition on this input resets the internal counters and controls and enables DATA OUT, ADDRESS, and I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock. A low-to-high transition disables ADDRESS and I/O CLOCK within a setup time plus two falling edges of the internal system clock.
DATA OUT	16	O	The 3-state serial output for the A/D conversion result. This output is in the high-impedance state when \overline{CS} is high and active when \overline{CS} is low. With a valid chip select, DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB value of the previous conversion result. The next falling edge of I/O CLOCK drives this output to the logic level corresponding to the next most significant bit, and the remaining bits are shifted out in order with the LSB appearing on the ninth falling edge of I/O CLOCK. On the tenth falling edge of I/O CLOCK, DATA OUT is driven to a low logic level so that serial interface data transfers of more than ten clocks produce zeroes as the unused LSBs.
EOC	19	O	End of conversion. This output goes from a high to a low logic level on the trailing edge of the tenth I/O CLOCK and remains low until the conversion is complete and data are ready for transfer.
GND	10	I	The ground return terminal for the internal circuitry. Unless otherwise noted, all voltage measurements are with respect to this terminal.
I/O CLOCK	18	I	Input/output clock. This terminal receives the serial I/O CLOCK input and performs the following four functions: 1) It clocks the four input address bits into the address register on the first four rising edges of the I/O CLOCK with the multiplex address available after the fourth rising edge. 2) On the fourth falling edge of I/O CLOCK, the analog input voltage on the selected multiplex input begins charging the capacitor array and continues to do so until the tenth falling edge of I/O CLOCK. 3) It shifts the nine remaining bits of the previous conversion data out on DATA OUT. 4) It transfers control of the conversion to the internal state controller on the falling edge of the tenth clock.
REF+	14	I	The upper reference voltage value (nominally V_{CC}) is applied to this terminal. The maximum input voltage range is determined by the difference between the voltage applied to this terminal and the voltage applied to the REF– terminal.
REF–	13	I	The lower reference voltage value (nominally ground) is applied to this terminal.
VCC	20	I	Positive supply voltage

detailed description

With chip select (\overline{CS}) inactive (high), the ADDRESS and I/O CLOCK inputs are initially disabled and DATA OUT is in the high-impedance state. When the serial interface takes \overline{CS} active (low), the conversion sequence begins with the enabling of I/O CLOCK and ADDRESS and the removal of DATA OUT from the high-impedance state. The serial interface then provides the 4-bit channel address to ADDRESS and the I/O CLOCK sequence to I/O CLOCK. During this transfer, the serial interface also receives the previous conversion result from DATA OUT. I/O CLOCK receives an input sequence that is between 10 and 16 clocks long from the host serial interface. The first four I/O clocks load the address register with the 4-bit address on ADDRESS, selecting the desired analog channel, and the next six clocks providing the control timing for sampling the analog input.



TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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detailed description (continued)

There are six basic serial-interface timing modes that can be used with the device. These modes are determined by the speed of I/O CLOCK and the operation of \overline{CS} as shown in Table 1. These modes are (1) a fast mode with a 10-clock transfer and \overline{CS} inactive (high) between conversion cycles, (2) a fast mode with a 10-clock transfer and \overline{CS} active (low) continuously, (3) a fast mode with an 11- to 16-clock transfer and \overline{CS} inactive (high) between conversion cycles, (4) a fast mode with a 16-bit transfer and \overline{CS} active (low) continuously, (5) a slow mode with an 11- to 16-clock transfer and \overline{CS} inactive (high) between conversion cycles, and (6) a slow mode with a 16-clock transfer and \overline{CS} active (low) continuously.

The MSB of the previous conversion appears at DATA OUT on the falling edge of \overline{CS} in mode 1, mode 3, and mode 5, on the rising edge of EOC in mode 2 and mode 4, and following the sixteenth clock falling edge in mode 6. The remaining nine bits are shifted out on the next nine falling edges of I/O CLOCK. Ten bits of data are transmitted to the host-serial interface through DATA OUT. The number of serial clock pulses used also depends on the mode of operation, but a minimum of ten clock pulses is required for conversion to begin. On the tenth clock falling edge, the EOC output goes low and returns to the high logic level when conversion is complete and the result can be read by the host. Also, on the tenth clock falling edge, the internal logic takes DATA OUT low to ensure that the remaining bit values are zero if the I/O CLOCK transfer is more than ten clocks long.

Table 1 lists the operational modes with respect to the state of \overline{CS} , the number of I/O serial transfer clocks that can be used, and the timing edge on which the MSB of the previous conversion appears at the output.

Table 1. Mode Operation

MODES		\overline{CS}	NO. OF I/O CLOCKS	MSB AT DATA OUT †	TIMING DIAGRAM
Fast Modes	Mode 1	High between conversion cycles	10	\overline{CS} falling edge	Figure 9
	Mode 2	Low continuously	10	EOC rising edge	Figure 10
	Mode 3	High between conversion cycles	11 to 16 ‡	\overline{CS} falling edge	Figure 11
	Mode 4	Low continuously	16 ‡	EOC rising edge	Figure 12
Slow Modes	Mode 5	High between conversion cycles	11 to 16 ‡	\overline{CS} falling edge	Figure 13
	Mode 6	Low continuously	16 ‡	16th clock falling edge	Figure 14

† These edges also initiate serial-interface communication.

‡ No more than 16 clocks should be used.

fast modes

The device is in a fast mode when the serial I/O CLOCK data transfer is completed before the conversion is completed. With a 10-clock serial transfer, the device can only run in a fast mode since a conversion does not begin until the falling edge of the tenth I/O CLOCK.

mode 1: fast mode, \overline{CS} inactive (high) between conversion cycles, 10-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer is ten clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables the I/O CLOCK and ADDRESS terminals within a setup time plus two falling edges of the internal system clock.

mode 2: fast mode, \overline{CS} active (low) continuously, 10-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer is ten clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions; the rising edge of EOC then begins each sequence by removing DATA OUT from the low logic level, allowing the MSB of the previous conversion to appear immediately on this output.



TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

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mode 3: fast mode, \overline{CS} inactive (high) between conversion cycles, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables the I/O CLOCK and ADDRESS terminals within a setup time plus two falling edges of the internal system clock.

mode 4: fast mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions; the rising edge of EOC then begins each sequence by removing DATA OUT from the low logic level, allowing the MSB of the previous conversion to appear immediately on this output.

slow modes

In a slow mode, the conversion is completed before the serial I/O CLOCK data transfer is completed. A slow mode requires a minimum 11-clock transfer into I/O CLOCK, and the rising edge of the eleventh clock must occur before the conversion period is complete; otherwise, the device loses synchronization with the host-serial interface and \overline{CS} has to be toggled to initialize the system. The eleventh rising edge of the I/O CLOCK must occur within 9.5 μ s after the tenth I/O clock falling edge.

mode 5: slow mode, \overline{CS} inactive (high) between conversion cycles, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables the I/O CLOCK and ADDRESS terminals within a setup time plus two falling edges of the internal system clock.

mode 6: slow mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. The falling edge of the sixteenth I/O CLOCK then begins each sequence by removing DATA OUT from the low state, allowing the MSB of the previous conversion to appear immediately at DATA OUT. The device is then ready for the next 16-clock transfer initiated by the serial interface.

address bits

The 4-bit analog channel-select address for the next conversion cycle is presented to the ADDRESS terminal (MSB first) and is clocked into the address register on the first four leading edges of I/O CLOCK. This address selects one of 14 inputs (11 analog inputs or three internal test inputs).

analog inputs and test modes

The 11 analog inputs and the three internal test inputs are selected by the 14-channel multiplexer according to the input address as shown in Tables 2 and 3. The input multiplexer is a break-before-make type to reduce input-to-input noise injection resulting from channel switching.

Sampling of the analog input starts on the falling edge of the fourth I/O CLOCK, and sampling continues for six I/O CLOCK periods. The sample is held on the falling edge of the tenth I/O CLOCK. The three test inputs are applied to the multiplexer, sampled, and converted in the same manner as the external analog inputs.

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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analog inputs and test modes (continued)

Table 2. Analog-Channel-Select Address

ANALOG INPUT SELECTED	VALUE SHIFTED INTO ADDRESS INPUT	
	BINARY	HEX
A0	0000	0
A1	0001	1
A2	0010	2
A3	0011	3
A4	0100	4
A5	0101	5
A6	0110	6
A7	0111	7
A8	1000	8
A9	1001	9
A10	1010	A

Table 3. Test-Mode-Select Address

INTERNAL SELF-TEST VOLTAGE SELECTED†	VALUE SHIFTED INTO ADDRESS INPUT		OUTPUT RESULT (HEX)‡
	BINARY	HEX	
$\frac{V_{ref+} - V_{ref-}}{2}$	1011	B	200
V_{ref-}	1100	C	000
V_{ref+}	1101	D	3FF

† V_{ref+} is the voltage applied to the REF+ input, and V_{ref-} is the voltage applied to the REF- input.

‡ The output results shown are the ideal values and vary with the reference stability and with internal offsets.

converter and analog input

The CMOS threshold detector in the successive-approximation conversion system determines each bit by examining the charge on a series of binary-weighted capacitors (see Figure 1). In the first phase of the conversion process, the analog input is sampled by closing the S_C switch and all S_T switches simultaneously. This action charges all the capacitors to the input voltage.

In the next phase of the conversion process, all S_T and S_C switches are opened and the threshold detector begins identifying bits by identifying the charge (voltage) on each capacitor relative to the reference (REF-) voltage. In the switching sequence, ten capacitors are examined separately until all ten bits are identified and then the charge-convert sequence is repeated. In the first step of the conversion phase, the threshold detector looks at the first capacitor (weight = 512). Node 512 of this capacitor is switched to the REF+ voltage, and the equivalent nodes of all the other capacitors on the ladder are switched to REF-. If the voltage at the summing node is greater than the trip point of the threshold detector (approximately one-half V_{CC}), a 0 bit is placed in the output register and the 512-weight capacitor is switched to REF-. If the voltage at the summing node is less than the trip point of the threshold detector, a 1 bit is placed in the register and the 512-weight capacitor remains connected to REF+ through the remainder of the successive-approximation process. The process is repeated for the 256-weight capacitor, the 128-weight capacitor, and so forth down the line until all bits are counted.



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converter and analog input (continued)

With each step of the successive-approximation process, the initial charge is redistributed among the capacitors. The conversion process relies on charge redistribution to count and weigh the bits from MSB to LSB.

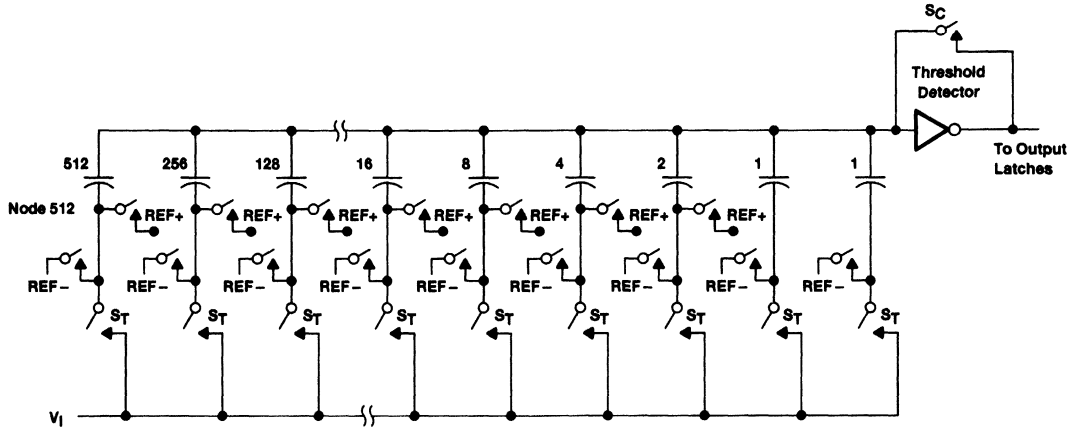


Figure 1. Simplified Model of the Successive-Approximation System

chip-select operation

The trailing edge of \overline{CS} starts all modes of operation, and \overline{CS} can abort a conversion sequence in any mode. A high-to-low transition on \overline{CS} within the specified time during an ongoing cycle aborts the cycle, and the device returns to the initial state (the contents of the output data register remain at the previous conversion result). Exercise care to prevent \overline{CS} from being taken low close to completion of conversion because the output data can be corrupted.

reference voltage inputs

There are two reference inputs used with the device: REF + and REF -. These voltage values establish the upper and lower limits of the analog input to produce a full-scale and zero reading, respectively. The values of REF +, REF -, and the analog input should not exceed the positive supply or be lower than GND consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF + and at zero when the input signal is equal to or lower than REF -.

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	-0.5 V to 6.5 V
Input voltage range, V_I	-0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O	-0.3 V to $V_{CC} + 0.3$ V
Positive reference voltage, V_{ref+}	$V_{CC} + 0.1$ V
Negative reference voltage, V_{ref-}	-0.1 V
Peak input current (any input)	±20 mA
Peak total input current (all inputs)	±30 mA
Operating free-air temperature range, T_A : TLC1542C, TLC1543C	0°C to 70°C
TLC1542I, TLC1543I	-40°C to 85°C
TLC1542Q, TLC1543Q	-40°C to 125°C
TLC1542M	-55°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to digital ground with REF- and GND wired together (unless otherwise noted).

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)		V_{CC}			V
Negative reference voltage, V_{ref-} (see Note 2)		0			V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)		2.5	V_{CC}	$V_{CC} + 0.2$	V
Analog input voltage (see Note 2)		0			V_{CC}
High-level control input voltage, V_{IH}	$V_{CC} = 4.5$ V to 5.5 V	2			V
Low-level control input voltage, V_{IL}	$V_{CC} = 4.5$ V to 5.5 V	0.8			V
Setup time, address bits at data input before I/O CLOCK↑, $t_{su(A)}$		100			ns
Hold time, address bits after I/O CLOCK↑, $t_h(A)$		0			ns
Hold time, \overline{CS} low after last I/O CLOCK↓, $t_h(CS)$		0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su(CS)}$ (see Note 3)		1.425			μs
Clock frequency at I/O CLOCK (see Note 4)		0			2.1
Pulse duration, I/O CLOCK high, $t_{wH(I/O)}$		190			ns
Pulse duration, I/O CLOCK low, $t_{wL(I/O)}$		190			ns
Transition time, I/O CLOCK, $t_{t(I/O)}$ (see Note 5 and Figure 6)		1			μs
Transition time, ADDRESS and \overline{CS} , $t_{t(CS)}$		10			μs
Operating free-air temperature, T_A	TLC1542C, TLC1543C	0			°C
	TLC1542I, TLC1543I	-40			
	TLC1542Q, TLC1543Q	-40			
	TLC1542M	-55			

NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (1111111111), while input voltages less than that applied to REF- convert as all zeros (0000000000). The device is functional with reference voltages down to 1 V ($V_{ref+} - V_{ref-}$); however, the electrical specifications are no longer applicable.

3. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after \overline{CS} ↓ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

4. For 11- to 16-bit transfers, after the tenth I/O CLOCK falling edge (≤ 2 V) at least 1 I/O CLOCK rising edge (≥ 2 V) must occur within 9.5 μs.

5. This is the time required for the clock input signal to fall from V_{IHmin} to V_{ILmax} or to rise from V_{ILmax} to V_{IHmin} . In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 1 μs for remote data-acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.



TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.5\text{ V to }5.5\text{ V}$, I/O CLOCK frequency = 2.1 MHz (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	V _{CC} = 4.5 V, I _{OH} = -1.6 mA	2.4			V
		V _{CC} = 4.5 V to 5.5 V, I _{OH} = -20 μA	V _{CC} -0.1			
V _{OL}	Low-level output voltage	V _{CC} = 4.5 V, I _{OL} = 1.6 mA			0.4	V
		V _{CC} = 4.5 V to 5.5 V, I _{OL} = 20 μA			0.1	
I _{OZ}	Off-state (high-impedance-state) output current	V _O = V _{CC} , \overline{CS} at V _{CC}			10	μA
		V _O = 0, \overline{CS} at V _{CC}			-10	
I _{IH}	High-level input current	V _I = V _{CC}		0.005	2.5	μA
I _{IL}	Low-level input current	V _I = 0		-0.005	-2.5	μA
I _{CC}	Operating supply current	\overline{CS} at 0 V		0.8	2.5	mA
Selected channel leakage current TLC1542/TLC1543 C, I, or Q		Selected channel at V _{CC} , Unselected channel at 0 V			1	μA
		Selected channel at 0 V, Unselected channel at V _{CC}			-1	
Selected channel leakage current TLC1542M		Selected channel at V _{CC} , Unselected channel at 0 V, T _A = 25°C			1	μA
		Selected channel at 0 V, Unselected channel at V _{CC} , T _A = 25°C			-1	
		Selected channel at V _{CC} , Unselected channel at 0 V			2.5	
		Selected channel at 0 V, Unselected channel at V _{CC}			-2.5	
Maximum static analog reference current into REF+		V _{ref+} = V _{CC} , V _{ref-} = GND			10	μA
C _i	Input capacitance	Analog inputs		7		pF
		Control inputs		5		

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q

10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.5\text{ V to }5.5\text{ V}$, I/O CLOCK frequency = 2.1 MHz (unless otherwise noted)

		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
E _L	Linearity error (see Note 6)	TLC1542C, I, or Q			±0.5	LSB
		TLC1543C, I, or Q			±1	LSB
		TLC1542M			±1	LSB
E _{ZS}	Zero-scale error (see Note 7)	TLC1542C, I, or Q	See Note 2		±0.5	LSB
		TLC1543C, I, or Q	See Note 2		±1	LSB
		TLC1542M	See Note 2		±1	LSB
E _{FS}	Full-scale error (see Note 7)	TLC1542C, I, or Q	See Note 2		±0.5	LSB
		TLC1543C, I, or Q	See Note 2		±1	LSB
		TLC1542M	See Note 2		±1	LSB
Total unadjusted error (see Note 8)		TLC1542C, I, or Q			±1	LSB
		TLC1543C, I, or Q			±1	LSB
		TLC1542M			±1	LSB
Self-test output code (see Table 3 and Note 9)		ADDRESS = 1011		512		
		ADDRESS = 1100		0		
		ADDRESS = 1101		1023		
t _{conv}	Conversion time	See timing diagrams			21	μs
t _c	total cycle time (access, sample, and conversion)	See timing diagrams and Note 10			21 +10 I/O CLOCK periods	μs
t _{acq}	Channel acquisition time (sample)	See timing diagrams and Note 10			6	I/O CLOCK periods
t _v	Valid time, DATA OUT remains valid after I/O CLOCK↓	See Figure 6	10			ns
t _{d(I/O-DATA)}	Delay time, I/O CLOCK↓ to DATA OUT valid	See Figure 6			240	ns
t _{d(I/O-EOC)}	Delay time, tenth I/O CLOCK↓ to EOC↓	See Figure 7		70	240	ns
t _{d(EOC-DATA)}	Delay time, EOC↑ to DATA OUT (MSB)	See Figure 8			100	ns

† All typical values are at T_A = 25°C.

NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (111111111), while input voltages less than that applied to REF- convert as all zeros (000000000). The device is functional with reference voltages down to 1 V (V_{ref+} - V_{ref-}); however, the electrical specifications are no longer applicable.

6. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
7. Zero-scale error is the difference between 000000000 and the converted output for zero input voltage; full-scale error is the difference between 111111111 and the converted output for full-scale input voltage.
8. Total unadjusted error comprises linearity, zero-scale, and full-scale errors.
9. Both the input address and the output codes are expressed in positive logic.
10. I/O CLOCK period = 1/(I/O CLOCK frequency) (see Figure 6)



TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.5\text{ V to }5.5\text{ V}$, I/O CLOCK frequency = 2.1 MHz (unless otherwise noted) (continued)

	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
t_{PZH}, t_{PZL}	Enable time, $\overline{CS}\downarrow$ to DATA OUT (MSB driven)			1.3	μs
t_{PHZ}, t_{PLZ}	Disable time, $\overline{CS}\uparrow$ to DATA OUT (high impedance)			150	ns
$t_r(\text{EOC})$	Rise time, EOC			300	ns
$t_f(\text{EOC})$	Fall time, EOC			300	ns
$t_r(\text{DATA})$	Rise time, data bus			300	ns
$t_f(\text{DATA})$	Fall time, data bus			300	ns
$t_d(\text{I/O-CS})$	Delay time, tenth I/O CLOCK \downarrow to $\overline{CS}\downarrow$ to abort conversion (see Note 11)			9	μs

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 11. Any transitions of \overline{CS} are recognized as valid only if the level is maintained for a setup time plus two falling edges of the internal clock (1.425 μs) after the transition.

PARAMETER MEASUREMENT INFORMATION

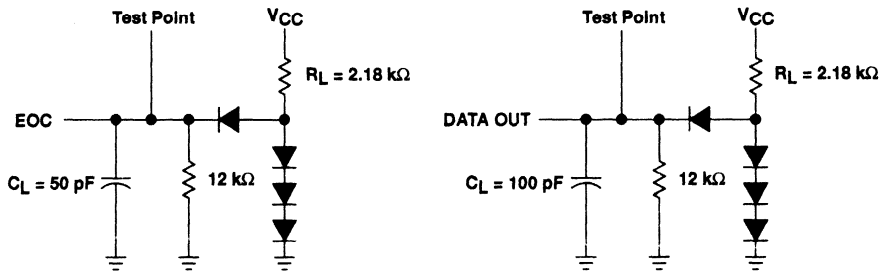


Figure 2. Load Circuits

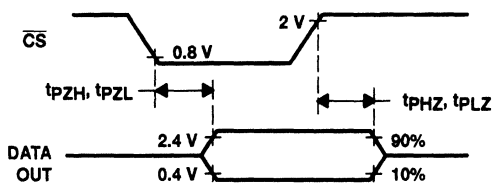


Figure 3. DATA OUT Enable and Disable Voltage Waveforms

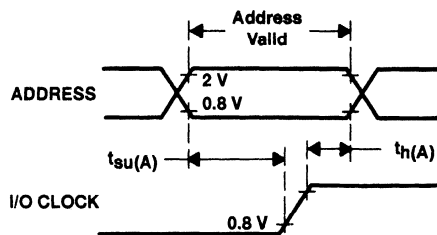


Figure 4. ADDRESS Setup and Hold Time Voltage Waveforms

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
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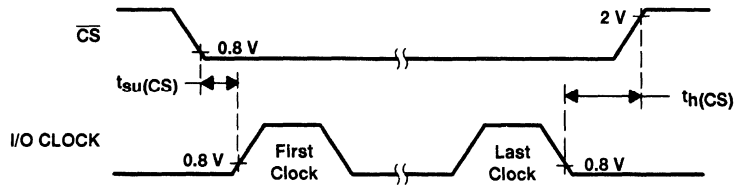


Figure 5. I/O CLOCK Setup and Hold Time Voltage Waveforms

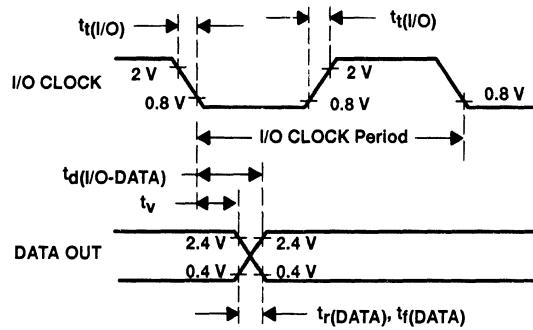


Figure 6. I/O CLOCK and DATA OUT Voltage Waveforms

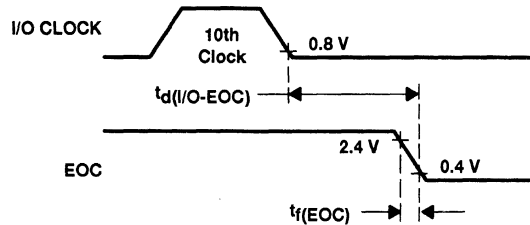


Figure 7. I/O CLOCK and EOC Voltage Waveforms

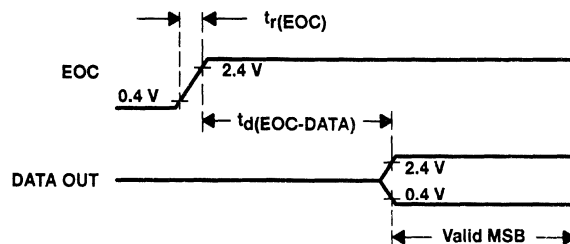


Figure 8. EOC and DATA OUT Voltage Waveforms

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
 SERIAL CONTROL AND 11 ANALOG INPUTS

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PARAMETER MEASUREMENT INFORMATION

timing diagrams

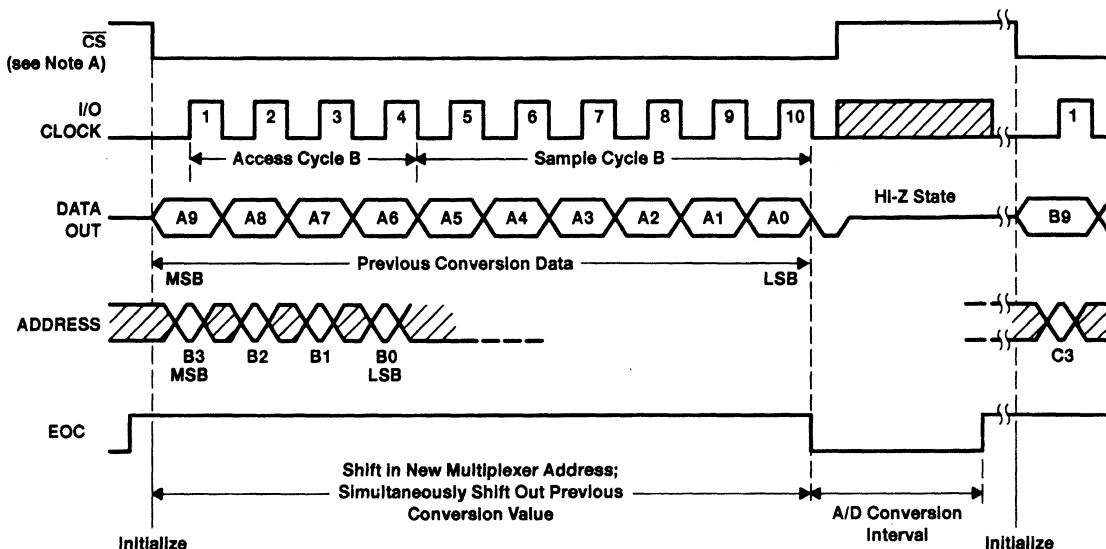


Figure 9. Timing for 10-Clock Transfer Using \overline{CS}

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after \overline{CS} before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
SERIAL CONTROL AND 11 ANALOG INPUTS
 SLAS052C - MARCH 1992 - REVISED MARCH 1995

PARAMETER MEASUREMENT INFORMATION

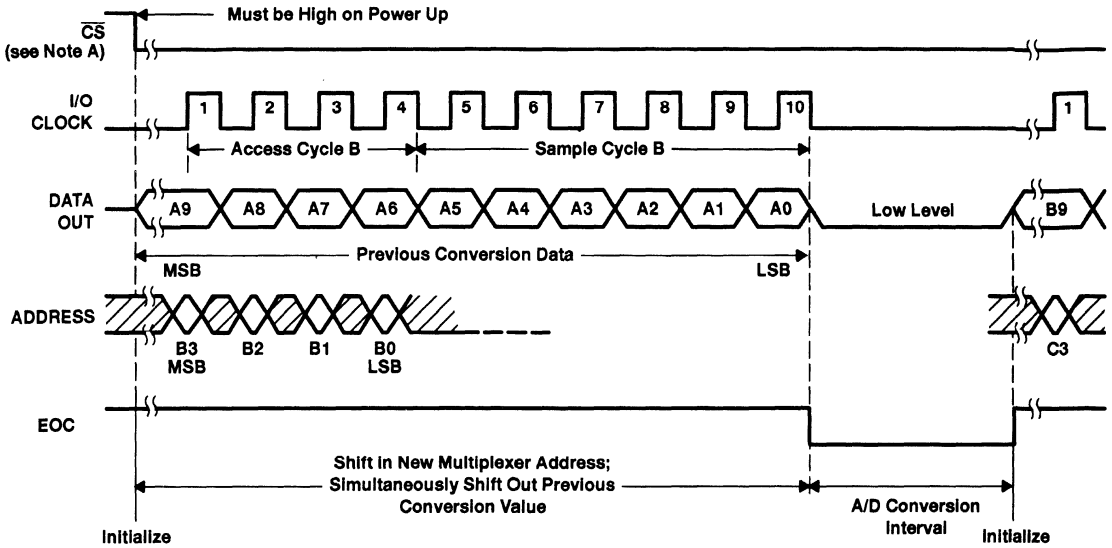


Figure 10. Timing for 10-Clock Transfer Not Using \overline{CS}

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
 SERIAL CONTROL AND 11 ANALOG INPUTS

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PARAMETER MEASUREMENT INFORMATION

timing diagrams (continued)

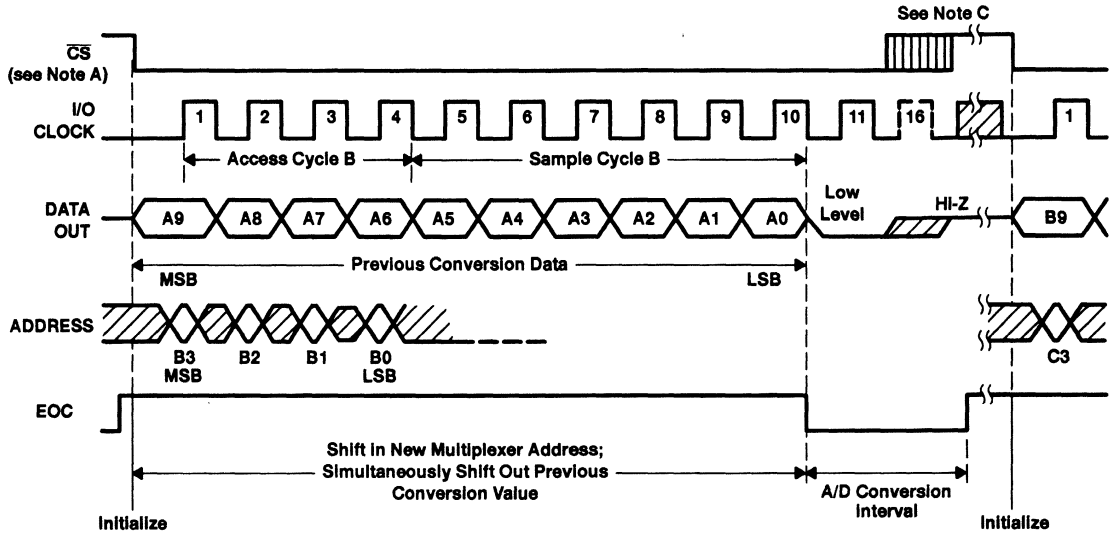


Figure 11. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Interval Shorter Than Conversion)

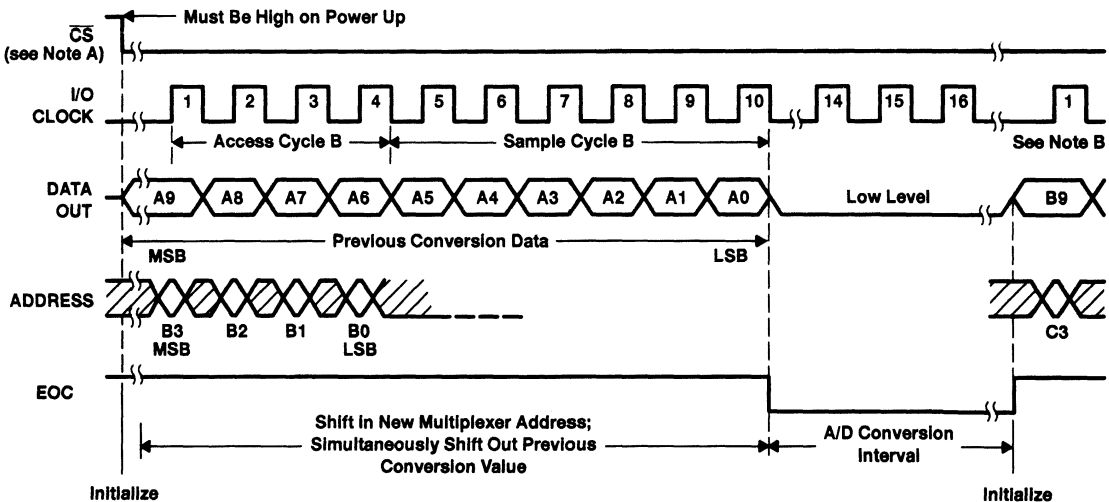


Figure 12. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Interval Shorter Than Conversion)

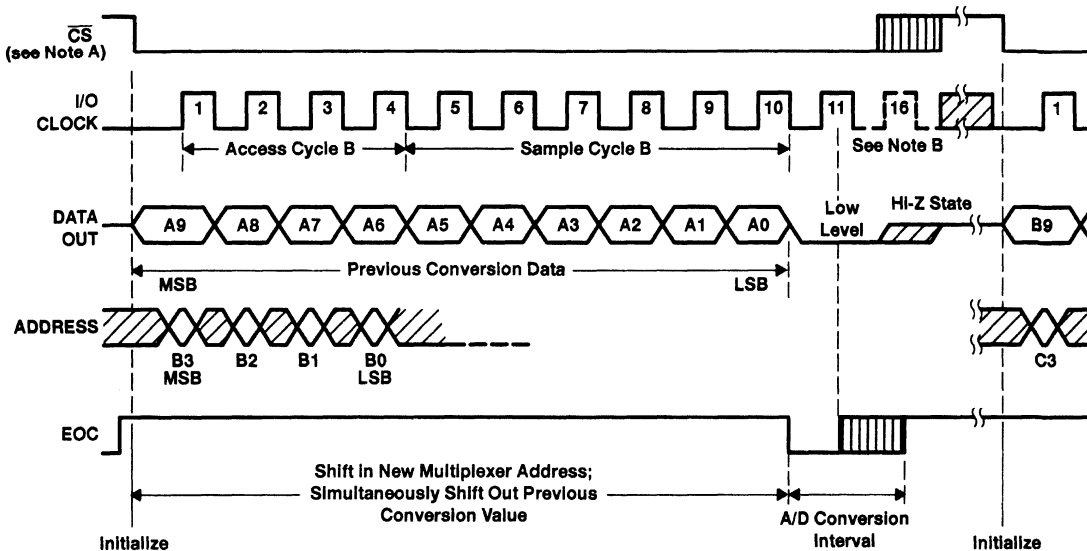
- NOTES:
- A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.
 - B. The first I/O CLOCK must occur after the rising edge of EOC.
 - C. A low-to-high transition of \overline{CS} disables ADDRESS and the I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock.

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
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PARAMETER MEASUREMENT INFORMATION

timing diagrams (continued)



- NOTES: A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.
- B. The 11th rising edge of the I/O CLOCK sequence must occur before the conversion is complete to prevent losing serial interface synchronization.

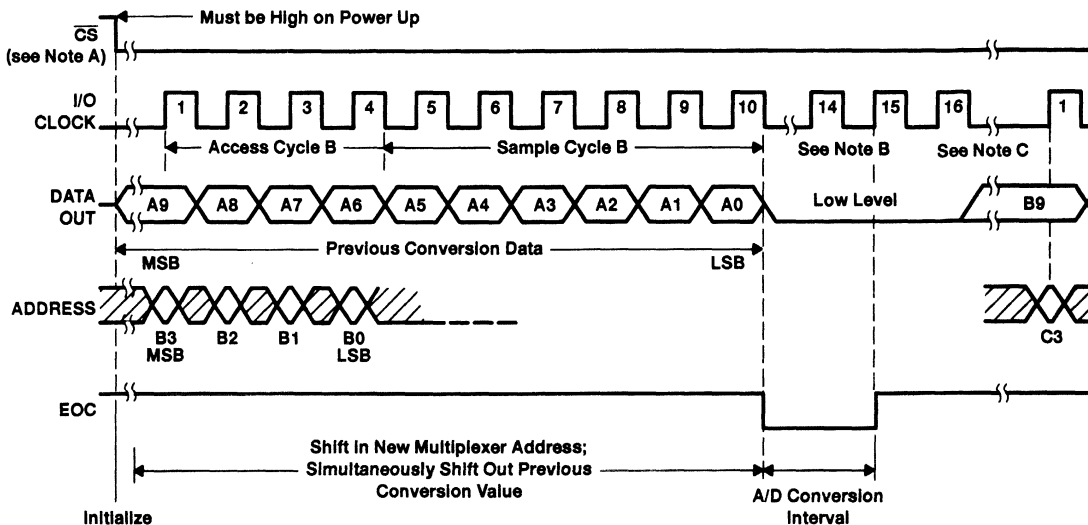
Figure 13. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Interval Longer Than Conversion)

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
 SERIAL CONTROL AND 11 ANALOG INPUTS

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PARAMETER MEASUREMENT INFORMATION

timing diagrams (continued)



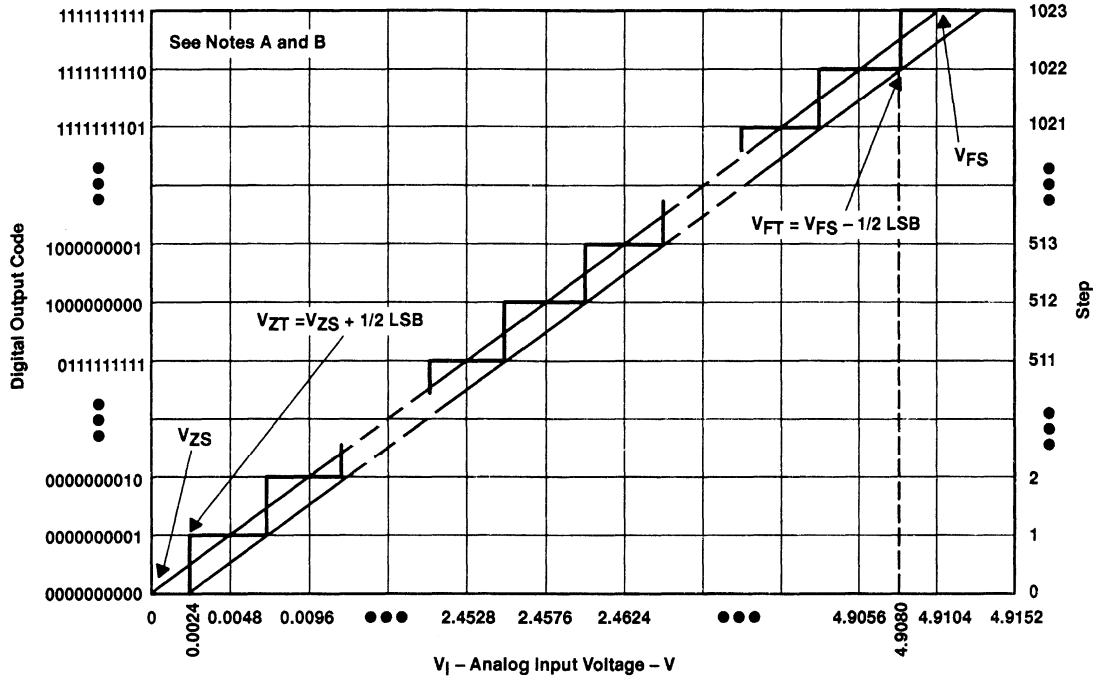
- NOTES: A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after \overline{CS} before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.
- B. The 11th rising edge of the I/O CLOCK sequence must occur before the conversion is complete to prevent losing serial interface synchronization.
- C. The I/O CLOCK sequence is exactly 16 clock pulses long.

Figure 14. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Interval Longer Than Conversion)

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
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APPLICATION INFORMATION



- NOTES: A. This curve is based on the assumption that V_{ref+} and V_{ref-} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 0.0024 V and the transition to full scale (V_{FT}) is 4.908 V. 1 LSB = 4.8 mV.
- B. The full-scale value (V_{FS}) is the step whose nominal midstep value has the highest absolute value. The zero-scale value (V_{ZS}) is the step whose nominal midstep value equals zero.

Figure 15. Ideal Conversion Characteristics

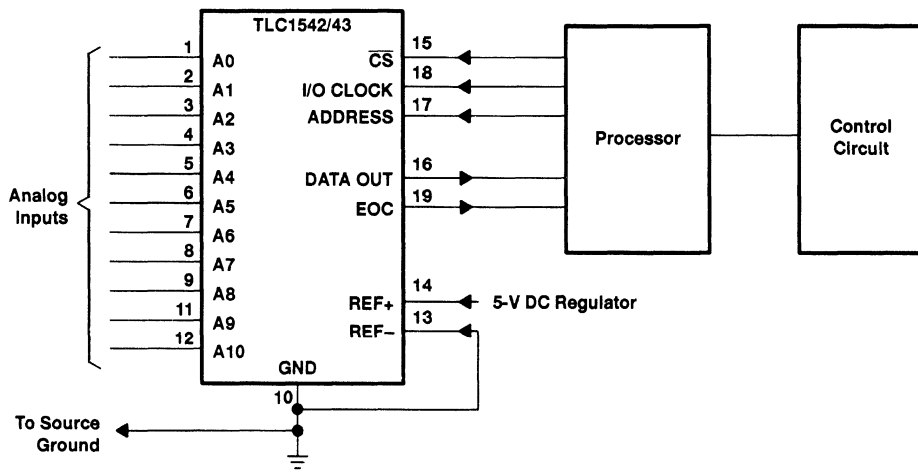


Figure 16. Serial Interface

TLC1542C, TLC1542I, TLC1542M, TLC1542Q, TLC1543C, TLC1543I, TLC1543Q
10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH
SERIAL CONTROL AND 11 ANALOG INPUTS

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APPLICATION INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 17, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S (1 - e^{-t_c / R_t C_i}) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/2048) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/2048) = V_S (1 - e^{-t_c / R_t C_i}) \quad (3)$$

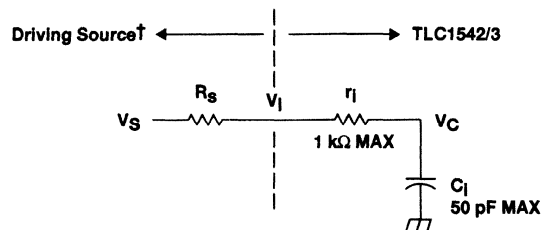
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(2048) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(2048) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at A0–A10
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Equivalent Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 17. Equivalent Input Circuit Including the Driving Source

TLC1549C, TLC1549I, TLC1549M 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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- 10-Bit-Resolution A/D Converter
- Inherent Sample and Hold
- Total Unadjusted Error . . . ± 1 LSB Max
- On-Chip System Clock
- Terminal Compatible With TLC549 and TLV1549
- CMOS Technology

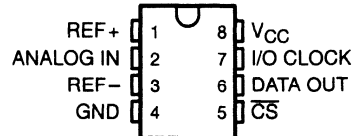
description

The TLC1549C, TLC1549I, and TLC1549M are 10-bit, switched-capacitor, successive-approximation analog-to-digital converters. These devices have two digital inputs and a 3-state output [chip select (\overline{CS}), input-output clock (I/O CLOCK), and data output (DATA OUT)] that provide a three-wire interface to the serial port of a host processor.

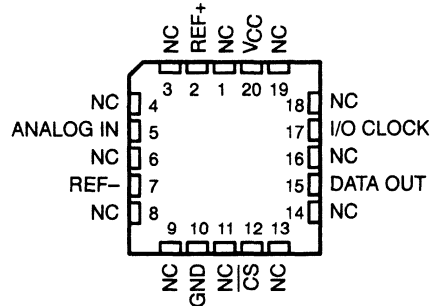
The sample-and-hold function is automatic. The converter incorporated in these devices features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating free-air temperature range.

The TLC1549C is characterized for operation from 0°C to 70°C. The TLC1549I is characterized for operation from -40°C to 85°C. The TLC1549M is characterized for operation over the full military temperature range of -55°C to 125°C.

D, JG, OR P PACKAGE
(TOP VIEW)



FK PACKAGE
(TOP VIEW)



NC – No internal connection

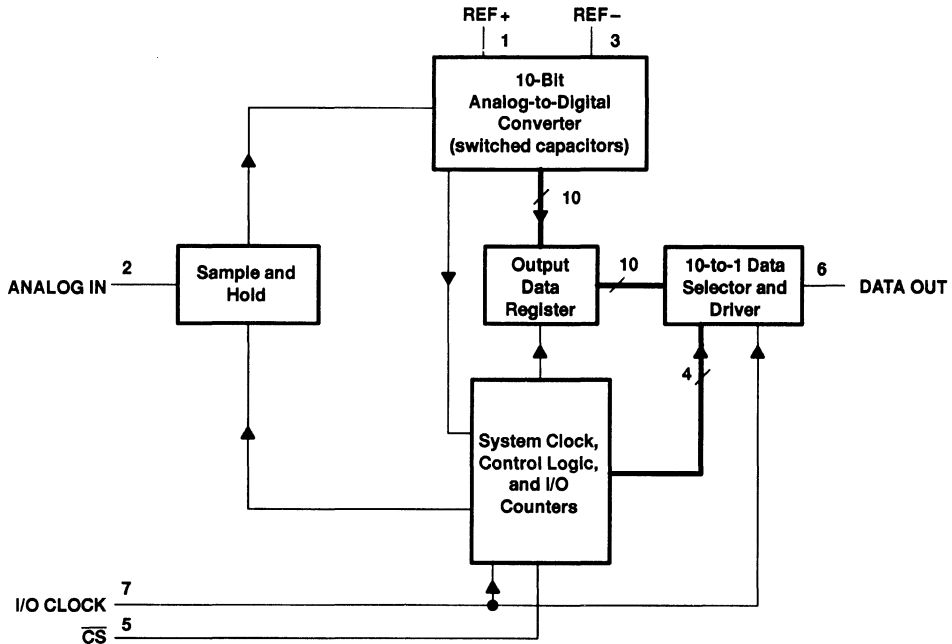
AVAILABLE OPTIONS

T _A	PACKAGE			
	SMALL OUTLINE (D)	CHIP CARRIER (FK)	CERAMIC DIP (JG)	PLASTIC DIP (P)
0°C to 70°C	TLC1549CD	—	—	TLC1549CP
-40°C to 85°C	TLC1549ID	—	—	TLC1549IP
-55°C to 125°C	—	TLC1549MFK	TLC1549MJG	—

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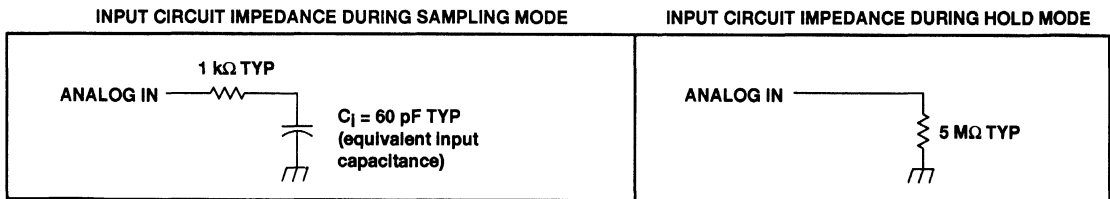
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functional block diagram



Terminal numbers shown are for the D, JG, and P packages only.

typical equivalent inputs



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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANALOG IN	2	I	Analog signal input. The driving source impedance should be $\leq 1 \text{ k}\Omega$. The external driving source to ANALOG IN should have a current capability $\geq 10 \text{ mA}$.
$\overline{\text{CS}}$	5	I	Chip select. A high-to-low transition on $\overline{\text{CS}}$ resets the internal counters and controls and enables DATA OUT and I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock. A low-to-high transition disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.
DATA OUT	6	O	This 3-state serial output for the A/D conversion result is in the high-impedance state when $\overline{\text{CS}}$ is high and active when $\overline{\text{CS}}$ is low. With a valid chip select, DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB value of the previous conversion result. The next falling edge of I/O CLOCK drives DATAOUT to the logic level corresponding to the next most significant bit, and the remaining bits are shifted out in order with the LSB appearing on the ninth falling edge of I/O CLOCK. On the tenth falling edge of I/O CLOCK, DATA OUT is driven to a low logic level so that serial interface data transfers of more than ten clocks produce zeroes as the unused LSBs.
GND	4		The ground return for internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.
I/O CLOCK	7	I	Input/output clock. I/O CLOCK receives the serial I/O CLOCK input and performs the following three functions: 1) On the third falling edge of I/O CLOCK, the analog input voltage begins charging the capacitor array and continues to do so until the tenth falling edge of I/O CLOCK. 2) It shifts the nine remaining bits of the previous conversion data out on DATA OUT. 3) It transfers control of the conversion to the internal state controller on the falling edge of the tenth clock.
REF +	1	I	The upper reference voltage value (nominally V_{CC}) is applied to REF+. The maximum input voltage range is determined by the difference between the voltage applied to REF+ and the voltage applied to REF-.
REF -	3	I	The lower reference voltage value (nominally ground) is applied to REF-.
V_{CC}	8		Positive supply voltage

detailed description

With chip select ($\overline{\text{CS}}$) inactive (high), I/O CLOCK is initially disabled and DATA OUT is in the high-impedance state. When the serial interface takes $\overline{\text{CS}}$ active (low), the conversion sequence begins with the enabling of I/O CLOCK and the removal of DATA OUT from the high-impedance state. The serial interface then provides the I/O CLOCK sequence to I/O CLOCK and receives the previous conversion result from DATA OUT. I/O CLOCK receives an input sequence that is between 10 and 16 clocks long from the host serial interface. The first ten I/O clocks provide the control timing for sampling the analog input.

There are six basic serial interface timing modes that can be used with the TLC1549. These modes are determined by the speed of I/O CLOCK and the operation of $\overline{\text{CS}}$ as shown in Table 1. These modes are (1) a fast mode with a 10-clock transfer and $\overline{\text{CS}}$ inactive (high) between transfers, (2) a fast mode with a 10-clock transfer and $\overline{\text{CS}}$ active (low) continuously, (3) a fast mode with an 11- to 16-clock transfer and $\overline{\text{CS}}$ inactive (high) between transfers, (4) a fast mode with a 16-bit transfer and $\overline{\text{CS}}$ active (low) continuously, (5) a slow mode with an 11- to 16-clock transfer and $\overline{\text{CS}}$ inactive (high) between transfers, and (6) a slow mode with a 16-clock transfer and $\overline{\text{CS}}$ active (low) continuously.

The MSB of the previous conversion appears on DATA OUT on the falling edge of $\overline{\text{CS}}$ in mode 1, mode 3, and mode 5, within 21 μs from the falling edge of the tenth I/O CLOCK in mode 2 and mode 4, and following the sixteenth clock falling edge in mode 6. The remaining nine bits are shifted out on the next nine falling edges of I/O CLOCK. Ten bits of data are transmitted to the host serial interface through DATA OUT. The number of serial clock pulses used also depends on the mode of operation, but a minimum of ten clock pulses is required for conversion to begin. On the tenth clock falling edge, the internal logic takes DATA OUT low to ensure that the remaining bit values are zero if the I/O CLOCK transfer is more than ten clocks long.



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detailed description (continued)

Table 1 lists the operational modes with respect to the state of \overline{CS} , the number of I/O serial transfer clocks that can be used, and the timing on which the MSB of the previous conversion appears at the output.

Table 1. Mode Operation

MODES		\overline{CS}	NO. OF I/O CLOCKS	MSB AT Terminal 6†	TIMING DIAGRAM
Fast Modes	Mode 1	High between conversion cycles	10	\overline{CS} falling edge	Figure 6
	Mode 2	Low continuously	10	Within 21 μ s	Figure 7
	Mode 3	High between conversion cycles	11 to 16‡	\overline{CS} falling edge	Figure 8
	Mode 4	Low continuously	16‡	Within 21 μ s	Figure 9
Slow Modes	Mode 5	High between conversion cycles	11 to 16‡	\overline{CS} falling edge	Figure 10
	Mode 6	Low continuously	16‡	16th clock falling edge	Figure 11

† This timing also initiates serial interface communication.

‡ No more than 16 clocks should be used.

All the modes require a minimum period of 21 μ s after the falling edge of the tenth I/O CLOCK before a new transfer sequence can begin. During a serial I/O CLOCK data transfer, \overline{CS} must be active (low) so that I/O CLOCK is enabled. When \overline{CS} is toggled between data transfers (modes 1, 3, and 5), the transitions at \overline{CS} are recognized as valid only if the level is maintained for a minimum period of 1.425 μ s after the transition. If the transfer is more than ten I/O clocks (modes 3, 4, 5, and 6), the rising edge of the eleventh clock must occur within 9.5 μ s after the falling edge of the tenth I/O CLOCK; otherwise, the device could lose synchronization with the host serial interface and \overline{CS} has to be toggled to restore proper operation.

fast modes

The TLC1549 is in a fast mode when the serial I/O CLOCK data transfer is completed within 21 μ s from the falling edge of the tenth I/O CLOCK. With a ten-clock serial transfer, the device can only run in a fast mode.

mode 1: fast mode, \overline{CS} inactive (high) between transfers, 10-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer is ten clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.

mode 2: fast mode, \overline{CS} active (low) continuously, 10-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer is ten clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. Within 21 μ s after the falling edge of the tenth I/O CLOCK, the MSB of the previous conversion appears at DATA OUT.

mode 3: fast mode, \overline{CS} inactive (high) between transfers, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.

mode 4: fast mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. Within 21 μ s after the falling edge of the tenth I/O CLOCK, the MSB of the previous conversion appears at DATA OUT.

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slow modes

In a slow mode, the serial I/O CLOCK data transfer is completed after 21 μ s from the falling edge of the tenth I/O CLOCK.

mode 5: slow mode, \overline{CS} inactive (high) between transfers, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.

mode 6: slow mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. The falling edge of the sixteenth I/O CLOCK then begins each sequence by removing DATA OUT from the low state, allowing the MSB of the previous conversion to appear immediately at DATA OUT. The device is then ready for the next-16 clock transfer initiated by the serial interface.

analog input sampling

Sampling of the analog input starts on the falling edge of the third I/O CLOCK, and sampling continues for seven I/O CLOCK periods. The sample is held on the falling edge of the tenth I/O CLOCK.

converter and analog input

The CMOS threshold detector in the successive-approximation conversion system determines each bit by examining the charge on a series of binary-weighted capacitors (see Figure 1). In the first phase of the conversion process, the analog input is sampled by closing the S_C switch and all S_T switches simultaneously. This action charges all the capacitors to the input voltage.

In the next phase of the conversion process, all S_T and S_C switches are opened and the threshold detector begins identifying bits by identifying the charge (voltage) on each capacitor relative to the reference (REF-) voltage. In the switching sequence, ten capacitors are examined separately until all ten bits are identified and then the charge-convert sequence is repeated. In the first step of the conversion phase, the threshold detector looks at the first capacitor (weight = 512). Node 512 of this capacitor is switched to the REF+ voltage, and the equivalent nodes of all the other capacitors on the ladder are switched to REF-. If the voltage at the summing node is greater than the trip point of the threshold detector (approximately one-half V_{CC}), a bit 0 is placed in the output register and the 512-weight capacitor is switched to REF-. If the voltage at the summing node is less than the trip point of the threshold detector, a bit 1 is placed in the register and this 512-weight capacitor remains connected to REF+ through the remainder of the successive-approximation process. The process is repeated for the 256-weight capacitor, the 128-weight capacitor, and so forth down the line until all bits are determined.

With each step of the successive-approximation process, the initial charge is redistributed among the capacitors. The conversion process relies on charge redistribution to determine the bits from MSB to LSB.

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converter and analog input (continued)

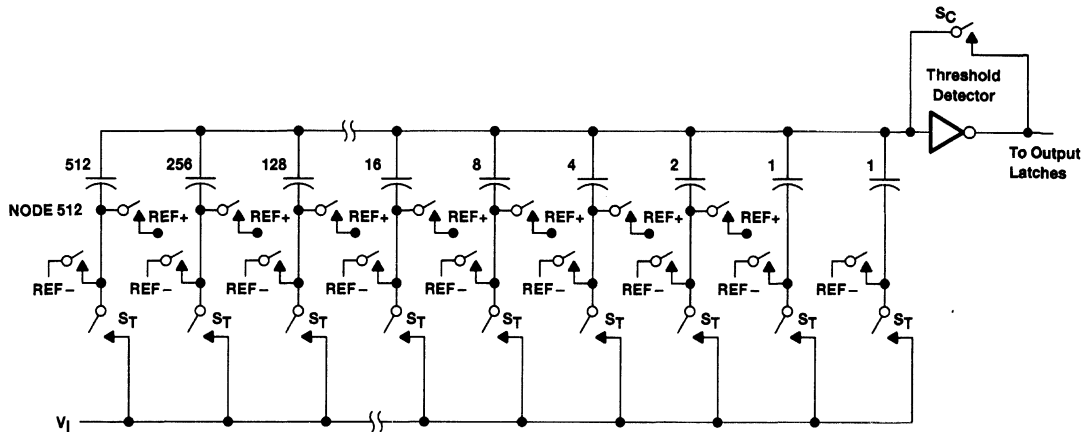


Figure 1. Simplified Model of the Successive-Approximation System

chip-select operation

The trailing edge of \overline{CS} starts all modes of operation, and \overline{CS} can abort a conversion sequence in any mode. A high-to-low transition on \overline{CS} within the specified time during an ongoing cycle aborts the cycle, and the device returns to the initial state (the contents of the output data register remain at the previous conversion result). Care should be exercised to prevent \overline{CS} from being taken low close to completion of conversion because the output data may be corrupted.

reference voltage inputs

There are two reference inputs used with the TLC1549: REF+ and REF-. These voltage values establish the upper and lower limits of the analog input to produce a full-scale and zero reading respectively. The values of REF+, REF-, and the analog input should not exceed the positive supply or be lower than GND consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF+ and at zero when the input signal is equal to or lower than REF-.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1):	TLC1549C, TLC1549I	–0.5 V to 6.5 V
	TLC1549M	–0.5 V to 6 V
Input voltage range, V_I (any input)		–0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O		–0.3 V to $V_{CC} + 0.3$ V
Positive reference voltage, V_{ref+}		$V_{CC} + 0.1$ V
Negative reference voltage, V_{ref-}		–0.1 V
Peak input current (any input)		± 20 mA
Peak total input current (all inputs)		± 30 mA
Operating free-air temperature range, T_A :	TLC1549C	0°C to 70°C
	TLC1549I	–40°C to 85°C
	TLC1549M	–55°C to 125°C
Storage temperature range, T_{stg}		–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds		260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to ground with REF– and GND wired together (unless otherwise noted).

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)		V_{CC}			V
Negative reference voltage, V_{ref-} (see Note 2)		0			V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)		2.5	V_{CC}	$V_{CC} + 0.2$	V
Analog input voltage (see Note 2)		0			V_{CC}
High-level control input voltage, V_{IH}	$V_{CC} = 4.5$ V to 5.5 V	2			V
Low-level control input voltage, V_{IL}	$V_{CC} = 4.5$ V to 5.5 V	0.8			V
Clock frequency at I/O CLOCK (see Note 3)		0			2.1
Setup time, \overline{CS} low before first I/O CLOCK \uparrow , $t_{su}(CS)$ (see Note 4)		1.425			μ s
Hold time, \overline{CS} low after last I/O CLOCK \downarrow , $t_h(CS)$		0			ns
Pulse duration, I/O CLOCK high, $t_{wH}(I/O)$		190			ns
Pulse duration, I/O CLOCK low, $t_{wL}(I/O)$		190			ns
Transition time, I/O CLOCK, $t_t(I/O)$ (see Note 5 and Figure 5)					1
Transition time, \overline{CS} , $t_t(CS)$					10
Operating free-air temperature, T_A		TLC1549C			0
		TLC1549I			70
		TLC1549M			85
		–55			125
					°C

- NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (1111111111), while input voltages less than that applied to REF– convert as all zeros (0000000000). The TLC1549 is functional with reference voltages down to 1 V ($V_{ref+} - V_{ref-}$); however, the electrical specifications are no longer applicable.
3. For 11- to 16-bit transfers, after the tenth I/O CLOCK falling edge (≤ 2 V) at least 1 I/O CLOCK rising edge (≥ 2 V) must occur within 9.5 μ s.
4. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to the I/O CLOCK. No attempt should be made to clock out the data until the minimum \overline{CS} setup time has elapsed.
5. This is the time required for the clock input signal to fall from V_{IHmin} to V_{ILmax} or to rise from V_{ILmax} to V_{IHmin} . In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 1 μ s for remote data-acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.5\text{ V to }5.5\text{ V}$, I/O CLOCK frequency = 2.1 MHz (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
V _{OH}	High-level output voltage	V _{CC} = 4.5 V, I _{OH} = -1.6 mA	2.4			V	
		V _{CC} = 4.5 V to 5.5 V, I _{OH} = -20 μA	V _{CC} -0.1				
V _{OL}	Low-level output voltage	V _{CC} = 4.5 V, I _{OL} = 1.6 mA			0.4	V	
		V _{CC} = 4.5 V to 5.5 V, I _{OL} = 20 μA			0.1		
I _{OZ}	Off-state (high-impedance-state) output current	V _O = V _{CC} , \overline{CS} at V _{CC}			10	μA	
		V _O = 0, \overline{CS} at V _{CC}			-10		
I _{IH}	High-level input current	V _I = V _{CC}	0.005		2.5	μA	
I _{IL}	Low-level input current	V _I = 0	-0.005		-2.5	μA	
I _{CC}	Operating supply current	\overline{CS} at 0 V	0.8		2.5	mA	
	Analog input leakage current	V _I = V _{CC}			1	μA	
		V _I = 0			-1		
	Maximum static analog reference current into REF+	V _{ref+} = V _{CC} , V _{ref-} = GND			10	μA	
C _i	Input capacitance	TLC1549C, I (Analog)	During sample cycle		30	55	pF
		TLC1549M (Analog)	During sample cycle		30		
		TLC1549C, I (Control)			5	15	
		TLC1549M (Control)			5		

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

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**operating characteristics over recommended operating free-air temperature range,
V_{CC} = V_{ref+} = 4.5 V to 5.5 V, I/O CLOCK frequency = 2.1 MHz**

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
E _L	Linearity error (see Note 6)			±1	LSB
E _{ZS}	Zero-scale error (see Note 7)	See Note 2		±1	LSB
E _{FS}	Full-scale error (see Note 7)	See Note 2		±1	LSB
	Total unadjusted error (see Note 8)			±1	LSB
t _{conv}	Conversion time	See Figures 6–10		21	μs
t _c	Total cycle time (access, sample, and conversion)	See Figures 6–10, See Note 9		21 + 10 I/O CLOCK periods	μs
t _v	Valid time, DATA OUT remains valid after I/O CLOCK↓	See Figure 5	10		ns
t _{d(I/O-DATA)}	Delay time, I/O CLOCK↓ to DATA OUT valid	See Figure 5		240	ns
t _{PZH, t_{PZL}}	Enable time, \overline{CS} ↓ to DATA OUT (MSB driven)	See Figure 3		1.3	μs
t _{PHZ, t_{PLZ}}	Disable time, \overline{CS} ↑ to DATA OUT (high impedance)	See Figure 3		180	ns
t _{r(bus)}	Rise time, data bus	See Figure 5		300	ns
t _{f(bus)}	Fall time, data bus	See Figure 5		300	ns
t _{d(I/O-CS)}	Delay time, tenth I/O CLOCK↓ to \overline{CS} ↓ to abort conversion (see Note 10)			9	μs

- NOTES:
2. Analog input voltages greater than that applied to REF + convert as all ones (111111111), while input voltages less than that applied to REF – convert as all zeros (000000000). The TLC1549 is functional with reference voltages down to 1 V (V_{ref+} – V_{ref-}); however, the electrical specifications are no longer applicable.
 6. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
 7. Zero error is the difference between 000000000 and the converted output for zero input voltage; full-scale error is the difference between 111111111 and the converted output for full-scale input voltage.
 8. Total unadjusted error comprises linearity, zero, and full-scale errors.
 9. I/O CLOCK period = 1/(I/O CLOCK frequency). Sampling begins on the falling edge of the third I/O CLOCK, continues for seven I/O CLOCK periods, and ends on the falling edge of the 10th I/O CLOCK (see Figure 5).
 10. Any transitions of \overline{CS} are recognized as valid only if the level is maintained for a minimum of a setup time plus two falling edges of the internal clock (1.425 μs) after the transition.



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PARAMETER MEASUREMENT INFORMATION

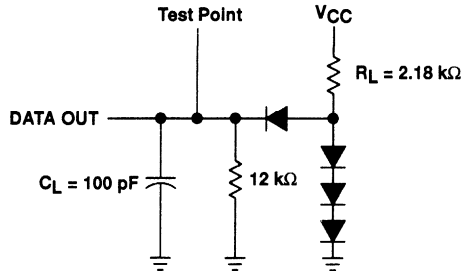


Figure 2. Load Circuit

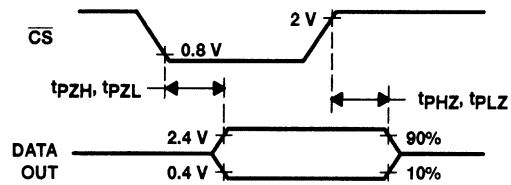


Figure 3. DATA OUT to Hi-Z Voltage Waveforms

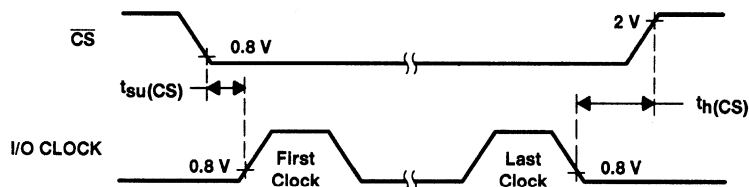


Figure 4. CS to I/O CLOCK Voltage Waveforms

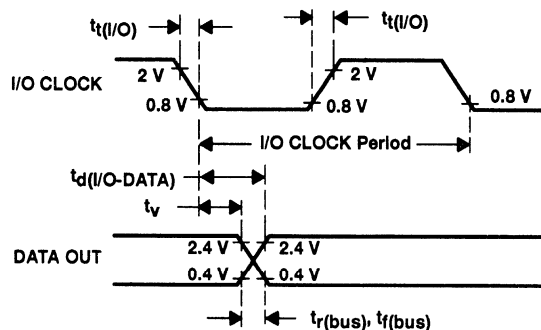


Figure 5. I/O CLOCK and DATA OUT Voltage Waveforms

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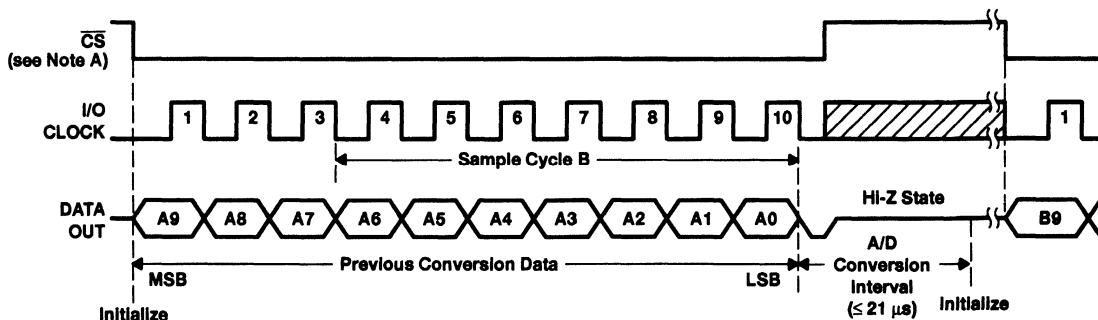


Figure 6. Timing for 10-Clock Transfer Using \overline{CS}

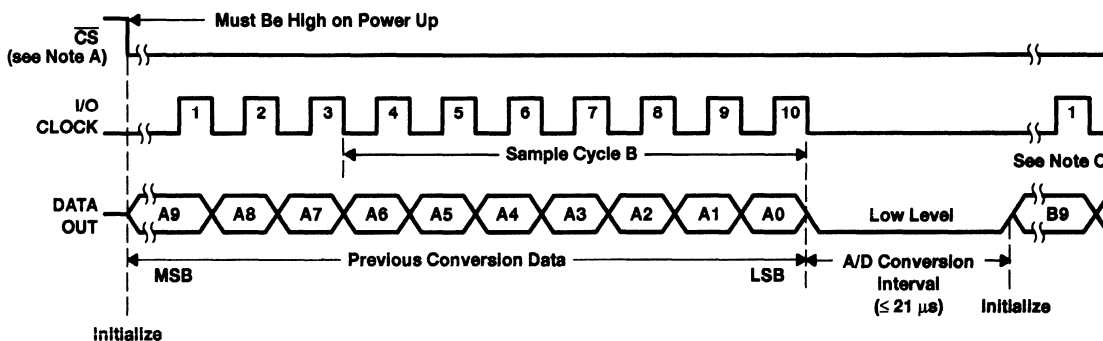


Figure 7. Timing for 10-Clock Transfer Not Using \overline{CS}

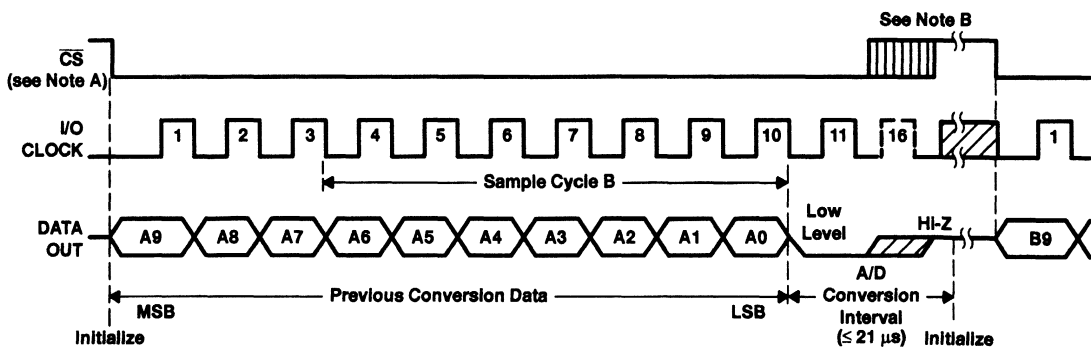


Figure 8. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Completed Within 21 μ s)

- NOTES:
- To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after \overline{CS} \downarrow before responding to the I/O CLOCK. No attempt should be made to clock out the data until the minimum \overline{CS} setup time has elapsed.
 - A low-to-high transition of \overline{CS} disables I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock.
 - The first I/O CLOCK must occur after the end of the previous conversion.

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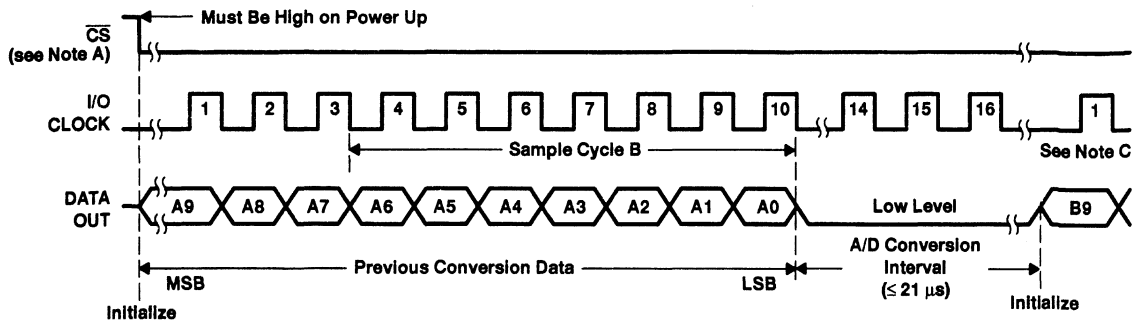


Figure 9. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Completed Within 21 μ s)

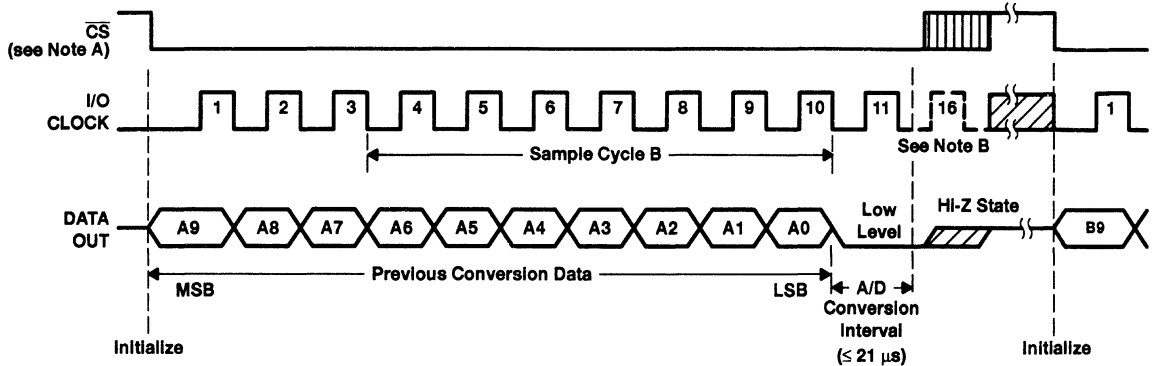


Figure 10. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Completed After 21 μ s)

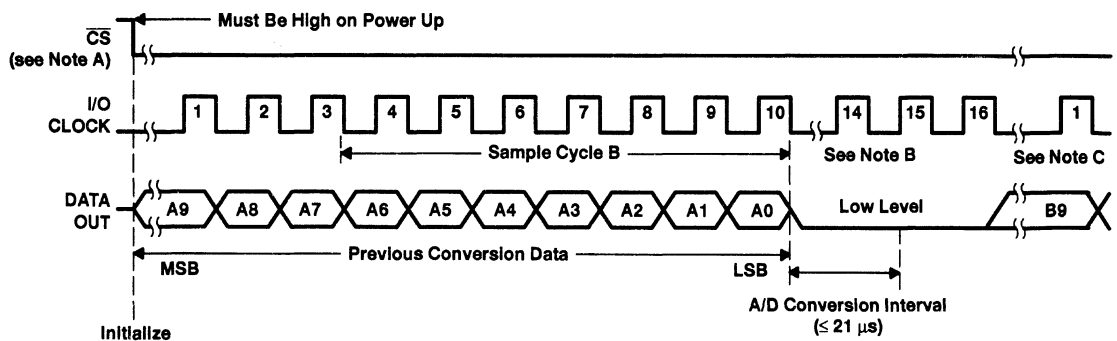


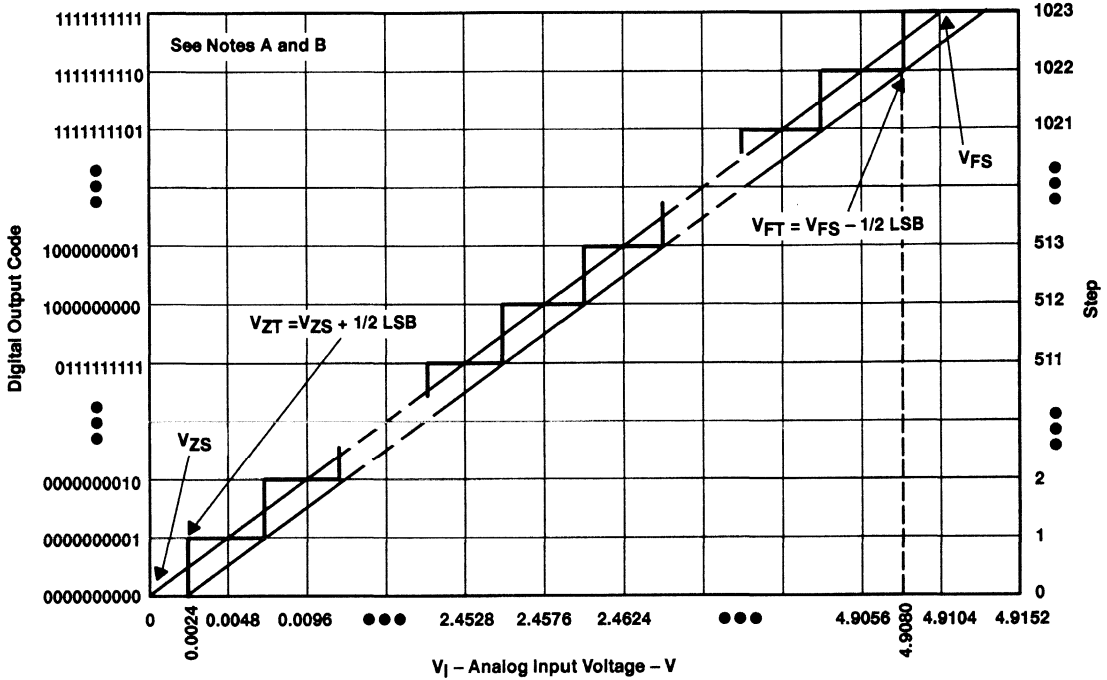
Figure 11. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Completed After 21 μ s)

- NOTES:
- To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a set up time plus two falling edges of the internal system clock after $\overline{CS} \downarrow$ before responding to the I/O CLOCK. No attempt should be made to clock out the data until the minimum \overline{CS} setup time has elapsed.
 - A low-to-high transition of \overline{CS} disables I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock.
 - The first I/O CLOCK must occur after the end of the previous conversion.

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APPLICATION INFORMATION



- NOTES: A. This curve is based on the assumption that V_{ref+} and V_{ref-} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 0.0024 V and the transition to full scale (V_{FT}) is 4.908 V. 1 LSB = 4.8 mV.
- B. The full-scale value (V_{FS}) is the step whose nominal midstep value has the highest absolute value. The zero-scale value (V_{ZS}) is the step whose nominal midstep value equals zero.

Figure 12. Ideal Conversion Characteristics

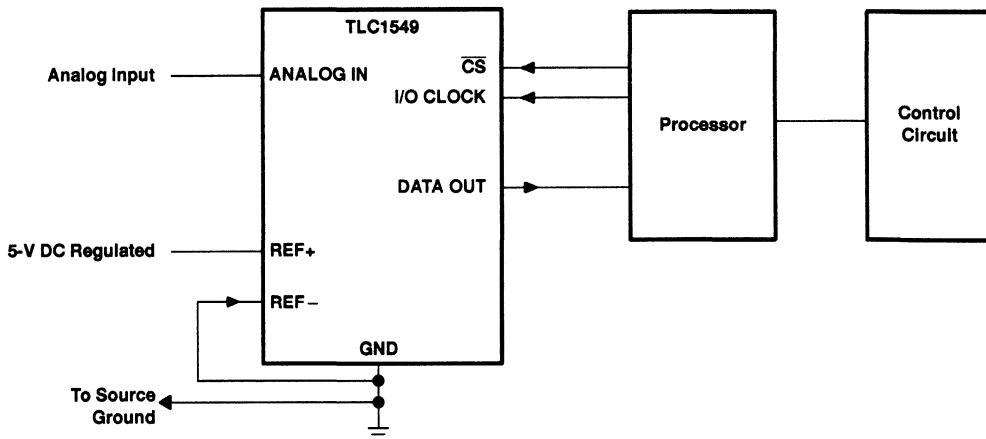


Figure 13. Typical Serial Interface

TLC1549C, TLC1549I, TLC1549M
10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL

SLAS059C – DECEMBER 1992 – REVISED MARCH 1995

APPLICATION INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 14, the time required to charge the analog input capacitance from 0 V to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S / 2048) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S / 2048) = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (3)$$

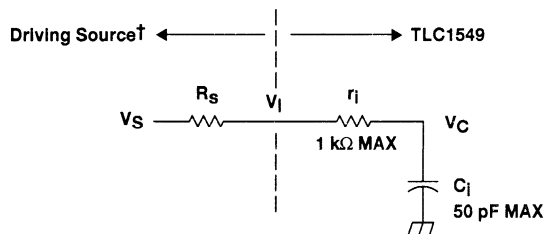
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(2048) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(2048) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at ANALOG IN
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 14. Equivalent Input Circuit Including the Driving Source

TLC1550I, TLC1550M, TLC1551I 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH PARALLEL OUTPUTS

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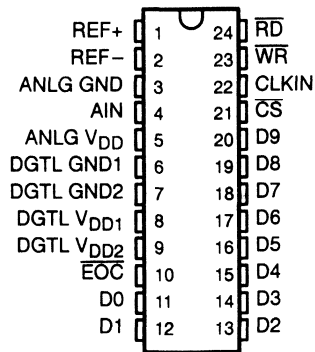
- Power Dissipation . . . 40 mW Max
- Advanced LinEPIC™ Single-Poly Process Provides Close Capacitor Matching for Better Accuracy
- Fast Parallel Processing for DSP and μP Interface
- Either External or Internal Clock Can Be Used
- Conversion Time . . . 6 μs
- Total Unadjusted Error . . . ± 1 LSB Max
- CMOS Technology

description

The TLC1550x and TLC1551 are data acquisition analog-to-digital converters (ADCs) using a 10-bit, switched-capacitor, successive-approximation network. A high-speed, 3-state parallel port directly interfaces to a digital signal processor (DSP) or microprocessor (μP) system data bus. D0 through D9 are the digital output terminals with D0 being the least significant bit (LSB). Separate power terminals for the analog and digital portions minimize noise pickup in the supply leads. Additionally, the digital power is divided into two parts to separate the lower current logic from the higher current bus drivers. An external clock can be applied to CLKIN to override the internal system clock if desired.

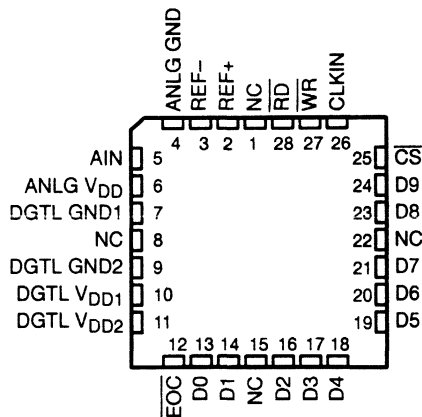
The TLC1550I and TLC1551I are characterized for operation from -40°C to 85°C . The TLC1550M is characterized over the full military range of -55°C to 125°C .

J† OR NW PACKAGE
(TOP VIEW)



† Refer to the mechanical data for the JW package.

FK OR FN PACKAGE
(TOP VIEW)



NC – No internal connection

AVAILABLE OPTIONS

T _A	PACKAGE			
	CERAMIC CHIP CARRIER (FK)	PLASTIC CHIP CARRIER (FN)	CERAMIC DIP (J)	PLASTIC DIP (NW)
-40°C to 85°C	–	TLC1550IFN TLC1551IFN	–	TLC1550INW TLC1551INW
-55°C to 125°C	TLC1550MFK	–	TLC1550MJ	–



This device contains circuits to protect its inputs and outputs against damage due to high static voltages or electrostatic fields. These circuits have been qualified to protect this device against electrostatic discharges (ESD) of up to 2 kV according to MIL-STD-883C, Method 3015; however, it is advised that precautions be taken to avoid application of any voltage higher than maximum-rated voltages to these high-impedance circuits. During storage or handling, the device leads should be shorted together or the device should be placed in conductive foam. In a circuit, unused inputs should always be connected to an appropriated logic voltage level, preferably either V_{CC} or ground.

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PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

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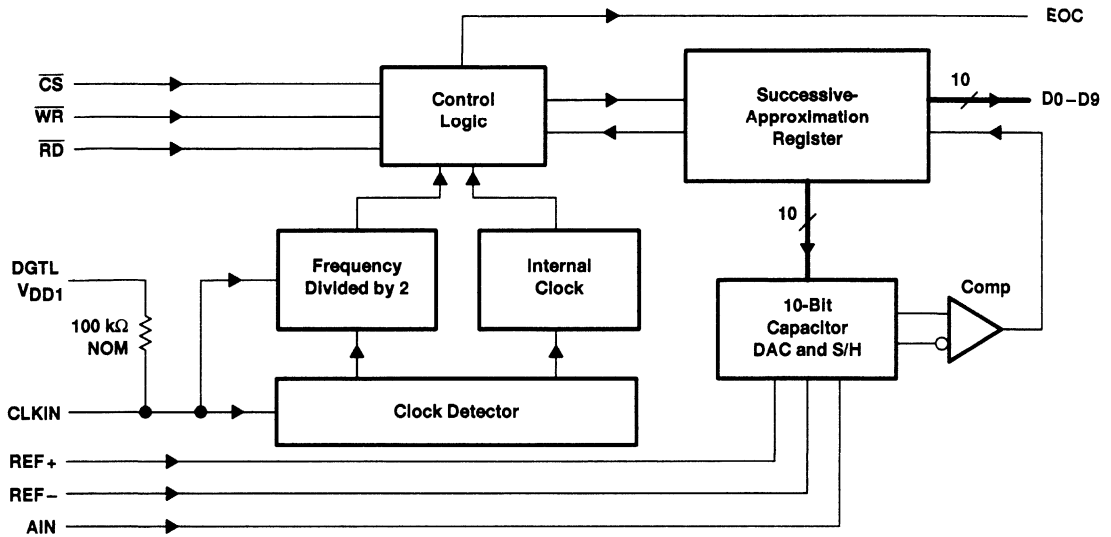
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On products compliant to MIL-STD-883, Class B, all parameters are tested unless otherwise noted. On all other products, production processing does not necessarily include testing of all parameters.

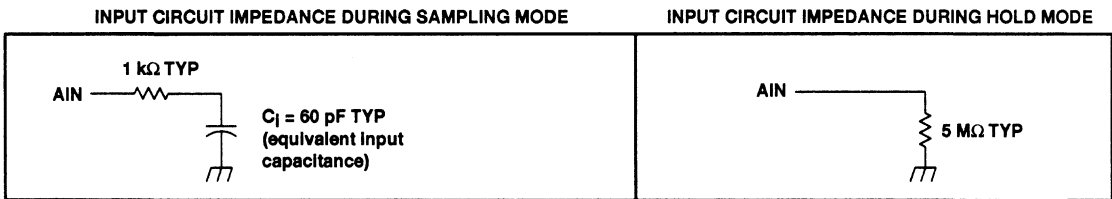
TLC1550I, TLC1550M, TLC1551I
10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH PARALLEL OUTPUTS

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functional block diagram



typical equivalent inputs



TLC1550I, TLC1550M, TLC1551I 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH PARALLEL OUTPUTS

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Terminal Functions

TERMINAL			DESCRIPTION
NAME	NO.†	NO.‡	
ANLG GND	4	3	Analog ground. The reference point for the voltage applied on terminals ANLG V_{DD} , AIN, REF+, and REF-.
AIN	5	4	Analog voltage input. The voltage applied to AIN is converted to the equivalent digital output.
ANLG V_{DD}	6	5	Analog positive power supply voltage. The voltage applied to this terminal is designated V_{DD3} .
CLKIN	26	22	Clock input. CLKIN is used for external clocking instead of using the internal system clock. It usually takes a few microseconds before the internal clock is disabled. To use the internal clock, CLKIN should be tied high or left unconnected.
\overline{CS}	25	21	Chip-select. \overline{CS} must be low for \overline{RD} or \overline{WR} to be recognized by the A/D converter.
D0	13	11	Data bus output. D0 is bit 1 (LSB).
D1	14	12	Data bus output. D1 is bit 2.
D2	16	13	Data bus output. D2 is bit 3.
D3	17	14	Data bus output. D3 is bit 4.
D4	18	15	Data bus output. D4 is bit 5.
D5	19	16	Data bus output. D5 is bit 6.
D6	20	17	Data bus output. D6 is bit 7.
D7	21	18	Data bus output. D7 is bit 8.
D8	23	19	Data bus output. D8 is bit 9.
D9	24	20	Data bus output. D9 is bit 10 (MSB).
DGTL GND1	7	6	Digital ground 1. The ground for power supply DGTL V_{DD1} and is the substrate connection.
DGTL GND2	9	7	Digital ground 2. The ground for power supply DGTL V_{DD2} .
DGTL V_{DD1}	10	8	Digital positive power-supply voltage 1. DGTL V_{DD1} supplies the logic. The voltage applied to DGTL V_{DD1} is designated V_{DD1} .
DGTL V_{DD2}	11	9	Digital positive power-supply voltage 2. DGTL V_{DD2} supplies only the higher-current output buffers. The voltage applied to DGTL V_{DD2} is designated V_{DD2} .
\overline{EOC}	12	10	End-of-conversion. \overline{EOC} goes low indicating that conversion is complete and the results have been transferred to the output latch. \overline{EOC} can be connected to the μP - or DSP-interrupt terminal or can be continuously polled.
\overline{RD}	28	24	Read input. When \overline{CS} is low and \overline{RD} is taken low, the data is placed on the data bus from the output latch. The output latch stores the conversion results at the most recent negative edge of \overline{EOC} . The falling edge of \overline{RD} resets \overline{EOC} to a high within the $t_d(\overline{EOC})$ specifications.
REF+	2	1	Positive voltage-reference input. Any analog input that is greater than or equal to the voltage on REF+ converts to 1111111111. Analog input voltages between REF+ and REF- convert to the appropriate result in a ratiometric manner.
REF-	3	2	Negative voltage reference input. Any analog input that is less than or equal to the voltage on REF- converts to 0000000000.
\overline{WR}	27	23	Write input. When \overline{CS} is low, conversion is started on the rising edge of \overline{WR} . On this rising edge, the ADC holds the analog input until conversion is completed. Before and after the conversion period, which is given by t_{conv} , the ADC remains in the sampling mode.

† Terminal numbers for FK and FN packages.

‡ Terminal numbers for J and NW packages.



TLC1550I, TLC1550M, TLC1551I

10-BIT ANALOG-TO-DIGITAL CONVERTERS

WITH PARALLEL OUTPUTS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{DD1} , V_{DD2} , and V_{DD3} (see Note 1)	6.5 V
Input voltage range, V_I (any input)	-0.3 V to $V_{DD} + 0.3$ V
Output voltage range, V_O	-0.3 V to $V_{DD} + 0.3$ V
Peak input current (any digital input)	± 10 mA
Peak total input current (all inputs)	± 30 mA
Operating free-air temperature range, T_A : TLC1550I, TLC1551I	-40°C to 85°C
TLC1550M	-55°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds: FK or FN package	260°C
Lead temperature 1.6 mm (1/16 inch) from the case for 10 seconds: J or NW package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: V_{DD1} is the voltage measured at DGTL V_{DD1} with respect to DGND1. V_{DD2} is the voltage measured at DGTL V_{DD2} with respect to the DGND2. V_{DD3} is the voltage measured at ANLG V_{DD} with respect to AGND. For these specifications, all ground terminals are tied together (and represent 0 V). When V_{DD1} , V_{DD2} , and V_{DD3} are equal, they are referred to simply as V_{DD} .

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD1} , V_{DD2} , V_{DD3}	4.75	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)	V_{DD3}			V
Negative reference voltage, V_{ref-} (see Note 2)	0			V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)	0.3		0.3	V
Analog input voltage range	0	V_{DD3}		V
High-level control input voltage, V_{IH}	2			V
Low-level control input voltage, V_{IL}				V
			0.8	
Input clock frequency, $f_{(CLKIN)}$	0.5	7.8		MHz
Setup time, \overline{CS} low before \overline{WR} or \overline{RD} goes low, $t_{su}(CS)$	0			ns
Hold time, \overline{CS} low after \overline{WR} or \overline{RD} goes high, $t_h(CS)$	0			ns
\overline{WR} or \overline{RD} pulse duration, $t_w(WR)$	50			ns
Input clock low pulse duration, $t_{wL}(CLKIN)$	40% of period		80% of period	
Operating free-air temperature, T_A	TLC155xI	-40	85	°C
	TLC1550M	-55	125	

NOTE 2: Analog input voltages greater than that applied to REF+ convert to all 1s (1111111111), while input voltages less than that applied to REF- convert to all 0s (0000000000). The total unadjusted error may increase as this differential voltage falls below 4.75 V.



TLC1550I, TLC1550M, TLC1551I
10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH PARALLEL OUTPUTS
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electrical characteristics over recommended operating free-air temperature range,
 $V_{DD} = V_{ref+} = 4.75$ to 5.5 V and $V_{ref-} = 0$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$V_{DD} = 4.75$ V, $I_{OH} = -360$ μ A	2.4			V
V_{OL}	Low-level output voltage	$V_{DD} = 4.75$ V, $I_{OL} = 2.4$ mA, $T_A = 25^\circ$ C			0.4	V
		$T_A = -55^\circ$ C to 125° C			0.5	
I_{OZ}	Off-state (high-impedance-state) output current	$V_O = V_{DD}$, \overline{CS} and \overline{RD} at V_{DD}			10	μ A
		$V_O = 0$, \overline{CS} and \overline{RD} at V_{DD}			-10	
I_{IH}	High-level input current	$V_I = V_{DD}$	0.005		2.5	μ A
I_{IL}	Low-level input current (except CLKIN)	$V_I = 0$	-2.5	-0.005		μ A
I_{iL}	Low-level input current (CLKIN)		-150	-50		μ A
I_{OS}	Short-circuit output current	$V_O = 5$ V, $T_A = 25^\circ$ C	7	14		mA
		$V_O = 0$, $T_A = 25^\circ$ C		-12	-6	
I_{DD}	Operating supply current	\overline{CS} low and \overline{RD} high	2		8	mA
C_i	Input capacitance	Analog inputs	60		90*	pF
		Digital inputs	5		15*	

* On products compliant to MIL-STD-883, Class B, this parameter is not production tested.

† All typical values are at $V_{DD} = 5$ V, $T_A = 25^\circ$ C.

TLC1550I, TLC1550M, TLC1551I

10-BIT ANALOG-TO-DIGITAL CONVERTERS

WITH PARALLEL OUTPUTS

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operating characteristics over recommended operating free-air temperature range with internal clock and minimum sampling time of 4 μ s, $V_{DD} = V_{ref+} = 5$ V and $V_{ref-} = 0$ (unless otherwise noted)

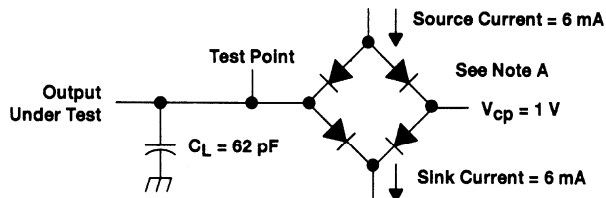
PARAMETER		TEST CONDITIONS	T_A †	MIN	TYP‡	MAX	UNIT
E _L	Linearity error	See Note 3	Full range			±0.5	LSB
						±1	
						±0.5	
						±1	
E _{ZS}	Zero-scale error	See Notes 2 and 4	Full range			±0.5	LSB
						±1	
						±0.5	
						±1	
E _{FS}	Full-scale error	See Notes 2 and 4	Full range			±0.5	LSB
						±1	
						±0.5	
						±1	
Total unadjusted error		See Note 5	Full range			±0.5	LSB
						±1	
						±1	
t _{conv}	Conversion time	f _{clock(external)} = 4.2 MHz or internal clock				6	μ s
t _{a(D)}	Data access time after \overline{RD} goes low	See Figure 3				35	ns
t _{v(D)}	Data valid time after \overline{RD} goes high			5	ns		
t _{dis(D)}	Disable time, delay time from \overline{RD} high to high impedance				30	ns	
t _{d(EOC)}	Delay time, \overline{RD} low to \overline{EOC} high			0	15	ns	

† Full range is -40°C to 85°C for the TL155xI devices and -55°C to 125°C for the TLC1550M.

‡ All typical values are at $V_{DD} = 5$ V, $T_A = 25^\circ$ C.

- NOTES:
- Analog input voltages greater than that applied to REF+ convert to all 1s (1111111111), while input voltages less than that applied to REF- convert to all 0s (0000000000). The total unadjusted error may increase as this differential voltage falls below 4.75 V.
 - Linearity error is the difference between the actual analog value at the transition between any two adjacent steps and its ideal value after zero-scale error and full-scale error have been removed.
 - Zero-scale error is the difference between the actual mid-step value and the nominal mid-step value at specified zero scale. Full-scale error is the difference between the actual mid-step value and the nominal mid-step value at specified full scale.
 - Total unadjusted error is the difference between the actual analog value at the transition between any two adjacent steps and its ideal value. It includes contributions from zero-scale error, full-scale error, and linearity error.

PARAMETER MEASUREMENT INFORMATION



V_{cp} = voltage commutation point for switching between source and sink currents

NOTE A: Equivalent load circuit of the Teradyne A500 tester for timing parameter measurement

Figure 1. Test Load Circuit

APPLICATION INFORMATION

simplified analog input analysis

Using the circuit in Figure 2, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/1024) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/512) = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (3)$$

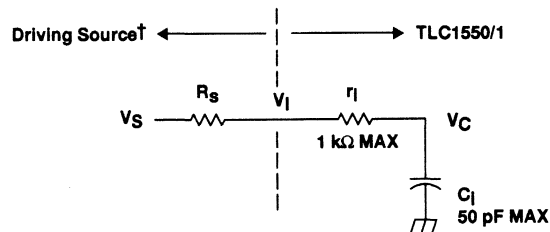
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(1024) \quad (4)$$

Therefore, with the values given, the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(1024) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input voltage at AIN
 V_S = External driving source voltage
 R_s = Source resistance
 r_i = Input resistance
 C_i = Input capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 2. Input Circuit Including the Driving Source

TLC1550I, TLC1550M, TLC1551I 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH PARALLEL OUTPUTS

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PRINCIPLES OF OPERATION

The operating sequence for complete data acquisition is shown in Figure 3. Processors can address the TLC1550 and TLC1551 as an external memory device by simply connecting the address lines to a decoder and the decoder output to \overline{CS} . Like other peripheral devices, the write (\overline{WR}) and read (\overline{RD}) input signals are valid only when \overline{CS} is low. Once \overline{CS} is low, the on-board system clock permits the conversion to begin with a simple write command and the converted data to be presented to the data bus with a simple read command. The device remains in a sampling (track) mode from the rising edge of \overline{EOC} until conversion begins with the rising edge of \overline{WR} , which initiates the hold mode. After the hold mode begins, the clock controls the conversion automatically. When the conversion is complete, the end-of-conversion (\overline{EOC}) signal goes low indicating that the digital data has been transferred to the output latch. Lowering \overline{CS} and \overline{RD} then resets \overline{EOC} and transfers the data to the data bus for the processor read cycle.

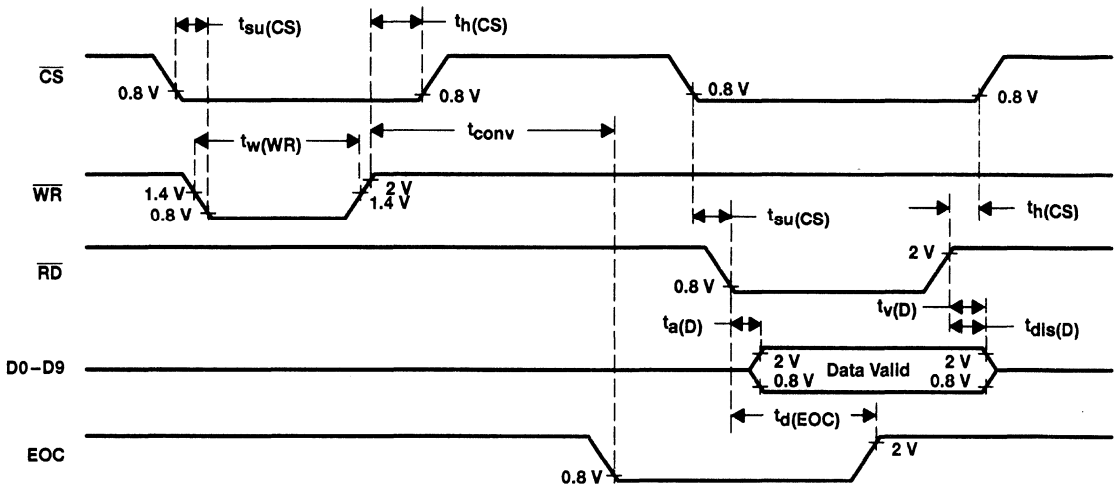


Figure 3. TLC1550 or TLC1551 Operating Sequence

TLC2543C, TLC2543I

12-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

SLAS079A – DECEMBER 1993 – REVISED DECEMBER 1994

- 12-Bit-Resolution A/D Converter
- 10- μ s Conversion Time Over Operating Temperature
- 11 Analog Input Channels
- 3 Built-In Self-Test Modes
- Inherent Sample and Hold
- Linearity Error . . . ± 1 LSB Max
- On-Chip System Clock
- End-of-Conversion (EOC) Output
- Unipolar or Bipolar Output Operation (Signed Binary With Respect to 1/2 the Applied Voltage Reference)
- Programmable MSB or LSB First
- Programmable Power Down
- Programmable Output Data Length
- CMOS Technology
- Application Report Available†

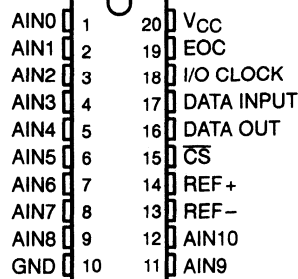
description

The TLC2543C and TLC2543I are 12-bit, switched-capacitor, successive-approximation, analog-to-digital converters. Each device has three control inputs [chip select (\overline{CS}), the input-output clock (I/O CLOCK), and the address input (DATA INPUT)] and is designed for communication with the serial port of a host processor or peripheral through a serial 3-state output. The device allows high-speed data transfers from the host.

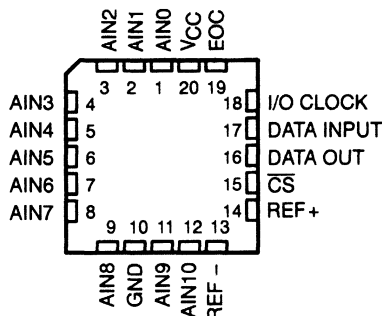
In addition to the high-speed converter and versatile control capability, the device has an on-chip 14-channel multiplexer that can select any one of 11 inputs or any one of three internal self-test voltages. The sample-and-hold function is automatic. At the end of conversion, the end-of-conversion (EOC) output goes high to indicate that conversion is complete. The converter incorporated in the device features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating temperature range.

The TLC2543 is available in the DB, DW, FN, and N packages. The TLC2543C is characterized for operation from 0°C to 70°C, and the TLC2543I is characterized for operation from -40°C to 85°C.

DB, DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

T _A	PACKAGE			
	SMALL OUTLINE (DB)‡	(DW)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC2543CDB	TLC2543CDW	TLC2543CFN	TLC2543CN
-40°C to 85°C	TLC2543IDB	TLC2543IDW	TLC2543IFN	TLC2543IN

‡ Available in tape and reel and ordered as the TLC2543CDBR or TLC2543IDBR.

† Microcontroller Based Data Acquisition Using the TLC2543 12-bit Serial-Out ADC (SLAA012)

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

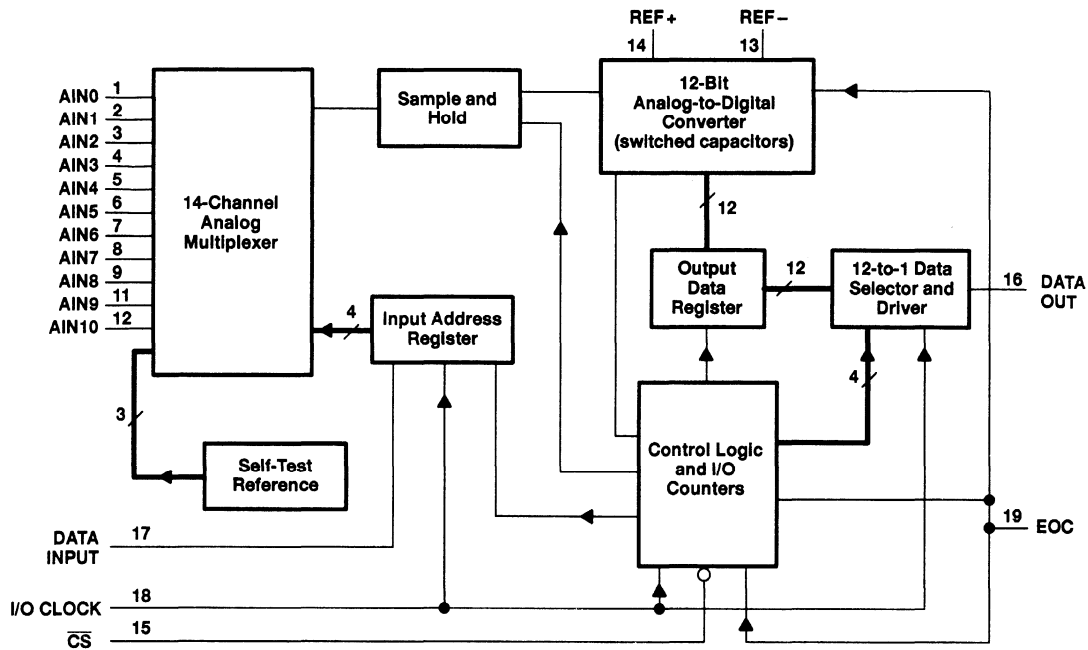


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TLC2543C, TLC2543I
12-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 ANALOG INPUTS

SLAS079A - DECEMBER 1993 - REVISED DECEMBER 1994

functional block diagram



TLC2543C, TLC2543I
12-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 ANALOG INPUTS
 SLAS079A – DECEMBER 1993 – REVISED DECEMBER 1994

Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AIN0 – AIN10	1–9, 11, 12	I	These 11 analog-signal inputs are internally multiplexed. The driving source impedance should be less than or equal to 50 Ω for 4.1-MHz I/O CLOCK operation and capable of slewing the analog input voltage into a capacitance of 60 pF.
\overline{CS}	15	I	Chip select. A high-to-low transition on \overline{CS} resets the internal counters and controls and enables DATA OUT, DATA INPUT, and I/O CLOCK. A low-to-high transition disables DATA INPUT and I/O CLOCK within a setup time.
DATA INPUT	17	I	Serial-data input. A 4-bit serial address selects the desired analog input or test voltage to be converted next. The serial data is presented with the MSB first and is shifted in on the first four rising edges of I/O CLOCK. After the four address bits are read into the address register, I/O CLOCK clocks the remaining bits in order.
DATA OUT	16	O	The 3-state serial output for the A/D conversion result. DATA OUT is in the high-impedance state when \overline{CS} is high and active when \overline{CS} is low. With a valid \overline{CS} , DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB/LSB value of the previous conversion result. The next falling edge of I/O CLOCK drives DATA OUT to the logic level corresponding to the next MSB/LSB, and the remaining bits are shifted out in order.
EOC	19	O	End of conversion goes from a high to a low logic level after the falling edge of the last I/O CLOCK and remains low until the conversion is complete and data are ready for transfer.
GND	10		The ground return terminal for the internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.
I/O CLOCK	18	I	Input/output clock. I/O CLOCK receives the serial input and performs the following four functions: 1. It clocks the eight input data bits into the input data register on the first eight rising edges of I/O CLOCK with the multiplexer address available after the fourth rising edge. 2. On the fourth falling edge of I/O CLOCK, the analog input voltage on the selected multiplexer input begins charging the capacitor array and continues to do so until the last falling edge of I/O CLOCK. 3. It shifts the 11 remaining bits of the previous conversion data out on DATA OUT. Data changes on the falling edge of I/O CLOCK. 4. It transfers control of the conversion to the internal state controller on the falling edge of the last I/O CLOCK.
REF +	14	I	The upper reference voltage value (nominally V_{CC}) is applied to REF+. The maximum input voltage range is determined by the difference between the voltage applied to this terminal and the voltage applied to the REF– terminal.
REF–	13	I	The lower reference voltage value (nominally ground) is applied to REF–.
VCC	20		Positive supply voltage

detailed description

Initially, with chip select (\overline{CS}) high, I/O CLOCK and DATA INPUT are disabled and DATA OUT is in the high-impedance state. \overline{CS} , going low, begins the conversion sequence by enabling I/O CLOCK and DATA INPUT and removes DATA OUT from the high-impedance state.

The input data is an 8-bit data stream consisting of a 4-bit analog channel address (D7–D4), a 2-bit data length select (D3–D2), an output MSB or LSB first bit (D1), and a unipolar or bipolar output select bit (D0) that are applied to DATA INPUT. The I/O CLOCK sequence applied to the I/O CLOCK terminal transfers this data to the input data register.

During this transfer, the I/O CLOCK sequence also shifts the previous conversion result from the output data register to DATA OUT. I/O CLOCK receives the input sequence of 8, 12, or 16 clocks long depending on the data-length selection in the input data register. Sampling of the analog input begins on the fourth falling edge of the input I/O CLOCK sequence and is held after the last falling edge of the I/O CLOCK sequence. The last falling edge of the I/O CLOCK sequence also takes EOC low and begins the conversion.

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converter operation

The operation of the converter is organized as a succession of two distinct cycles: 1) the I/O cycle and 2) the actual conversion cycle. The I/O cycle is defined by the externally provided I/O CLOCK and lasts 8, 12, or 16 clock periods, depending on the selected output data length.

1. I/O cycle

During the I/O cycle, two operations take place simultaneously.

- a. An 8-bit data stream consisting of address and control information is provided to DATA INPUT. This data is shifted into the device on the rising edge of the first eight I/O CLOCKS. DATA INPUT is ignored after the first eight clocks during 12 or 16 clock I/O transfers.
- b. The data output, with a length of 8, 12, or 16 bits, is provided serially on DATA OUT. If \overline{CS} is held low, the first output data bit occurs on the rising edge of EOC. If \overline{CS} is negated between conversions, the first output data bit occurs on the falling edge of \overline{CS} . This data is the result of the previous conversion period, and after the first output data bit, each succeeding bit is clocked out on the falling edge of each succeeding I/O CLOCK.

2. Conversion cycle

The conversion cycle is transparent to the user, and it is controlled by an internal clock synchronized to I/O CLOCK. During the conversion period, the device performs a successive-approximation conversion on the analog input voltage. The EOC output goes low at the start of the conversion cycle and goes high when conversion is complete and the output data register is latched. A conversion cycle is started only after the I/O cycle is completed, which minimizes the influence of external digital noise on the accuracy of the conversion.

power up and initialization

After power up, \overline{CS} must be taken from high to low to begin an I/O cycle. EOC is initially high, and the input data register is set to all zeroes. The contents of the output data register are random, and the first conversion result should be ignored. To initialize during operation, \overline{CS} is taken high and returned low to begin the next I/O cycle. The first conversion after the device has returned from the power-down state may not read accurately due to internal device settling.

operational terminology

Current (N) I/O cycle	The entire I/O CLOCK sequence that transfers address and control data into the data register and clocks the digital result from the previous conversion from DATA OUT
Current (N) conversion cycle	The conversion cycle starts immediately after the current I/O cycle. The end of the current I/O cycle is the last clock falling edge in the I/O CLOCK sequence. The current conversion result is loaded into the output register when conversion is complete.
Current (N) conversion result	The current conversion result is serially shifted out on the next I/O cycle.
Previous (N-1) conversion cycle	The conversion cycle just prior to the current I/O cycle
Next (N+1) I/O cycle	The I/O period that follows the current conversion cycle

Example: In the 12-bit mode, the result of the current conversion cycle is a 12-bit serial-data stream clocked out during the next I/O cycle. The current I/O cycle must be exactly 12 bits long to maintain synchronization, even if this corrupts the output data from the previous conversion. The current conversion is begun immediately after the twelfth falling edge of the current I/O cycle.

data input

The data input is internally connected to an 8-bit serial-input address and control register. The register defines the operation of the converter and the output data length. The host provides the data word with the MSB first. Each data bit is clocked in on the rising edge of the I/O CLOCK sequence (see Table 1 for the data register format).



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data input address bits

The four MSBs (D7 – D4) of the data register are used to address one of the 11 input channels, a reference-test voltage, or the power-down mode. The address bits affect the current conversion, which is the conversion that immediately follows the current I/O cycle. The reference voltage is nominally equal to $V_{ref+} - V_{ref-}$.

data output length

The next two bits (D3 and D2) of the data register select the output data length. The data-length selection is valid for the current I/O cycle (the cycle in which the data is read). The data-length selection, being valid for the current I/O cycle, allows device startup without losing I/O synchronization. A data length of 8, 12, or 16 bits can be selected. Since the converter has 12-bit resolution, a data length of 12 bits is suggested.

With D3 and D2 set to 00 or 10, the device is in the 12-bit data-length mode and the result of the current conversion is output as a 12-bit serial-data stream during the next I/O cycle. The current I/O cycle must be exactly 12 bits long for proper synchronization, even if this means corrupting the output data from a previous conversion. The current conversion is started immediately after the twelfth falling edge of the current I/O cycle.

With bits D3 and D2 set to 11, the 16-bit data-length mode is selected, which allows convenient communication with 16-bit serial interfaces. In the 16-bit mode, the result of the current conversion is output as a 16-bit serial-data stream during the next I/O cycle with the four LSBs always set to 0 (pad bits). The current I/O cycle must be exactly 16 bits long to maintain synchronization even if this means corrupting the output data from the previous conversion. The current conversion is immediately started after the sixteenth falling edge of the current I/O cycle.

With bits D3 and D2 set to 01, the 8-bit data-length mode is selected, which allows fast communication with 8-bit serial interfaces. In the 8-bit mode, the result of the current conversion is output as an 8-bit serial-data stream during the next I/O cycle. The current I/O cycle must be exactly 8 bits long to maintain synchronization, even if this means corrupting the output data from the previous conversion. The four LSBs of the conversion result are truncated and discarded. The current conversion is immediately started after the eighth falling edge of the current I/O cycle.

Since D3 and D2 take effect on the current I/O cycle when the data length is programmed, there can be a conflict with the previous cycle when the data-word length is changed from one cycle to the next. This may occur when the data format is selected to be least significant bit first, since at the time the data length change becomes effective (six rising edges of I/O CLOCK), the previous conversion result has already started shifting out.

In actual operation, if different data lengths are required within an application and the data length is changed between two conversions, no more than one conversion result can be corrupted and only if it is shifted out in LSB first format.

sampling period

During the sampling period, one of the analog inputs is internally connected to the capacitor array of the converter to store the analog input signal. The converter starts sampling the selected input immediately after the four address bits have been clocked into the input data register. Sampling starts on the fourth falling edge of I/O CLOCK. The converter remains in the sampling mode until the eighth, twelfth, or sixteenth falling edge of the I/O CLOCK depending on the data-length selection. After the EOC delay time from the last I/O CLOCK falling edge, the EOC output goes low indicating that the sampling period is over and the conversion period has begun. After EOC goes low, the analog input can be changed without affecting the conversion result. Since the delay from the falling edge of the last I/O CLOCK to EOC low is fixed, time-varying analog input signals can be digitized at a fixed rate without introducing systematic harmonic distortion or noise due to timing uncertainty.

After the 8-bit data stream has been clocked in, DATA INPUT should be held at a fixed digital level until EOC goes high (indicating the conversion is complete) to maximize the sampling accuracy and minimize the influence of external digital noise.

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data register, LSB first

D1 in the input data register (LSB first) is used to control the direction of the output binary data transfer. When D1 is set to 0, the conversion result is shifted out MSB first. When set to 1, the data is shifted out LSB first. Selection of MSB first or LSB first always affects the next I/O cycle and not the current I/O cycle. When changing from one data direction to another, the current I/O cycle is never disrupted.

data register, bipolar format

D0 in the input data register (BIP) is used to control the binary data format used to represent the conversion result. When D0 is set to 0, the conversion result is represented as unipolar (unsigned binary) data. Nominally, the conversion result of an input voltage equal to V_{ref-} is a code of all zeros (000 . . . 0), the conversion result of an input voltage equal to V_{ref+} is a code of all ones (111 . . . 1), and the conversion result of $(V_{ref+} + V_{ref-})/2$ is a code of a one followed by zeros (100 . . . 0).

When D0 is set to 1, the conversion result is represented as bipolar (signed binary) data. Nominally, conversion of an input voltage equal to V_{ref-} is a code of a 1 followed by zeros (100 . . . 0), conversion of an input voltage equal to V_{ref+} is a code of a 0 followed by all ones (011 . . . 1), and the conversion of $(V_{ref+} + V_{ref-})/2$ is a code of all zeros (000 . . . 0). The MSB is interpreted as the sign bit. The bipolar data format is related to the unipolar format in that the MSBs are always each other's complement.

Selection of the unipolar or bipolar format always affects the current conversion cycle, and the result is output during the next I/O cycle. When changing between unipolar and bipolar formats, the data output during the current I/O cycle is not affected.

EOC output

The EOC signal indicates the beginning and the end of conversion. In the reset state, EOC is always high. During the sampling period (beginning after the 4th falling edge of the I/O CLOCK sequence), EOC remains high until the internal sampling switch of the converter is safely opened. The opening of the sampling switch occurs after the eighth, twelfth, or sixteenth I/O CLOCK falling edge, depending on the data-length selection in the input data register. After the EOC signal goes low, the analog input signal can be changed without affecting the conversion result.

The EOC signal goes high again after the conversion is completed and the conversion result is latched into the output data register. The rising edge of EOC returns the converter to a reset state and a new I/O cycle begins. On the rising edge of EOC, the first bit of the current conversion result is on DATA OUT if \overline{CS} is low. If \overline{CS} is negated between conversions, the first bit of the current conversion result occurs at DATA OUT on the falling edge of \overline{CS} .

data format and pad bits

D3 and D2 of the input data register determine the number of significant bits in the digital output that represent the conversion result. The LSB-first bit determines the direction of the data transfer while the BIP bit determines the arithmetic conversion. The numerical data is always justified toward the MSB in any output format.

The internal conversion result is always 12 bits long. When an 8-bit data transfer is selected, the four LSBs of the internal result are discarded to provide a faster one-byte transfer. When a 12-bit transfer is used, all bits are transferred. When a 16-bit transfer is used, four LSB pad bits are always appended to the internal conversion result. In the LSB-first mode, four leading zeros are output. In the MSB-first mode, the last four bits output are zeros.

When \overline{CS} is held low continuously, the first data bit of the just completed conversion occurs on DATA OUT on the rising edge of EOC. When a new conversion is started after the last falling edge of I/O CLOCK, EOC goes low and the serial output is forced to a logic zero until EOC goes high again.

When \overline{CS} is negated between conversions, the first data bit occurs on DATA OUT on the falling edge of \overline{CS} . On each subsequent falling edge of I/O CLOCK after the first data bit appears, the data is changed to the next bit in the serial conversion result until the required number of bits has been output.



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chip-select Input (\overline{CS})

The chip-select input (\overline{CS}) is used to enable and disable the device. During normal operation, \overline{CS} should be low. Although the use of \overline{CS} is not necessary to synchronize a data transfer, it can be brought high between conversions to coordinate the data transfer of several devices sharing the same bus.

When \overline{CS} is brought high, the serial-data output is immediately brought to the high-impedance state, releasing its output data line to other devices that may share it. After an internally generated debounce time, I/O CLOCK is inhibited, thus preventing any further change in the internal state.

When \overline{CS} is subsequently brought low again, the device is reset. \overline{CS} must be held low for an internal debounce time before the reset operation takes effect. After \overline{CS} is debounced low, I/O CLOCK must remain inactive (low) for a minimum time before a new I/O cycle can start.

\overline{CS} can be used to interrupt any ongoing data transfer or any ongoing conversion. If \overline{CS} is debounced low long enough before the end of the current conversion cycle, the previous conversion result is saved in the internal output buffer and shifted out during the next I/O cycle.

power-down features

When a binary address of 1110 is clocked into the input data register during the first four I/O CLOCK cycles, the power-down mode is selected. Power down is activated on the falling edge of the fourth I/O CLOCK pulse.

During power down, all internal circuitry is put in a low-current standby mode. No conversions are performed, and the internal output buffer keeps the previous conversion cycle data results, provided that all digital inputs are held above $V_{CC} - 0.5$ V or below 0.5 V. The I/O logic remains active so the current I/O cycle must be completed even when the power-down mode is selected. Upon power-on reset and before the first I/O cycle, the converter normally begins in the power-down mode. The device remains in the power-down mode until a valid (other than 1110) input address is clocked in. Upon completion of that I/O cycle, a normal conversion is performed with the results being shifted out during the next I/O cycle.

analog input, test, and power-down mode

The 11 analog inputs, three internal voltages, and power-down mode are selected by the input multiplexer according to the input addresses shown in Tables 2, 3, and 4. The input multiplexer is a break-before-make type to reduce input-to-input noise rejection resulting from channel switching. Sampling of the analog input starts on the falling edge of the fourth I/O CLOCK and continues for the remaining I/O CLOCK pulses. The sample is held on the falling edge of the last I/O CLOCK pulse. The three internal test inputs are applied to the multiplexer, sampled, and converted in the same manner as the external analog inputs. The first conversion after the device has returned from the power-down state may not read accurately due to internal device settling.

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Table 1. Input-Register Format

FUNCTION SELECT	INPUT DATA BYTE							
	ADDRESS BITS				L1	L0	LSBF	BIP
	D7 (MSB)	D6	D5	D4	D3	D2	D1	D0 (LSB)
Select input channel								
AIN0 _____	0	0	0	0				
AIN1 _____	0	0	0	1				
AIN2 _____	0	0	1	0				
AIN3 _____	0	0	1	1				
AIN4 _____	0	1	0	0				
AIN5 _____	0	1	0	1				
AIN6 _____	0	1	1	0				
AIN7 _____	0	1	1	1				
AIN8 _____	1	0	0	0				
AIN9 _____	1	0	0	1				
AIN10 _____	1	0	1	0				
Select test voltage								
(V _{ref+} - V _{ref-})/2 _____	1	0	1	1				
V _{ref-} _____	1	1	0	0				
V _{ref+} _____	1	1	0	1				
Software power down _____	1	1	1	0				
Output data length								
8 bits _____					0	1		
12 bits _____					X	0		
16 bits _____					1	1		
Output data format								
MSB first _____							0	
LSB first _____							1	
Unipolar (binary) _____								0
Bipolar (2s complement) _____								1

Table 2. Analog-Channel-Select Address

ANALOG INPUT SELECTED	VALUE SHIFTED INTO DATA INPUT	
	BINARY	HEX
AIN0	0000	0
AIN1	0001	1
AIN2	0010	2
AIN3	0011	3
AIN4	0100	4
AIN5	0101	5
AIN6	0110	6
AIN7	0111	7
AIN8	1000	8
AIN9	1001	9
AIN10	1010	A

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Table 3. Test-Mode-Select Address

INTERNAL SELF-TEST VOLTAGE SELECTED†	VALUE SHIFTED INTO DATA INPUT		UNIPOLAR OUTPUT RESULT (HEX)‡
	BINARY	HEX	
$\frac{V_{ref+} - V_{ref-}}{2}$	1011	B	200
V_{ref-}	1100	C	000
V_{ref+}	1101	D	3FF

† V_{ref+} is the voltage applied to REF+, and V_{ref-} is the voltage applied to REF-.

‡ The output results shown are the ideal values and may vary with the reference stability and with internal offsets.

Table 4. Power-Down-Select Address

INPUT COMMAND	VALUE SHIFTED INTO DATA INPUT		RESULT
	BINARY	HEX	
Power down	1110	E	$I_{CC} \leq 25 \mu A$

converter and analog input

The CMOS threshold detector in the successive-approximation conversion system determines each bit by examining the charge on a series of binary-weighted capacitors (see Figure 1). In the first phase of the conversion process, the analog input is sampled by closing the S_C switch and all S_T switches simultaneously. This action charges all the capacitors to the input voltage.

In the next phase of the conversion process, all S_T and S_C switches are opened and the threshold detector begins identifying bits by identifying the charge (voltage) on each capacitor relative to the reference (REF-) voltage. In the switching sequence, 12 capacitors are examined separately until all 12 bits are identified and the charge-convert sequence is repeated. In the first step of the conversion phase, the threshold detector looks at the first capacitor (weight = 4096). Node 4096 of this capacitor is switched to the REF+ voltage, and the equivalent nodes of all the other capacitors on the ladder are switched to REF-. If the voltage at the summing node is greater than the trip point of the threshold detector (approximately one-half V_{CC}), a bit 0 is placed in the output register and the 4096-weight capacitor is switched to REF-. If the voltage at the summing node is less than the trip point of the threshold detector, a bit 1 is placed in the register and this 4096-weight capacitor remains connected to REF+ through the remainder of the successive-approximation process. The process is repeated for the 2048-weight capacitor, the 1024-weight capacitor, and so forth, down the line until all bits are determined. With each step of the successive-approximation process, the initial charge is redistributed among the capacitors. The conversion process relies on charge redistribution to determine the bits from MSB to LSB.

reference voltage inputs

There are two reference inputs used with the device, the voltages applied to the REF+ and REF- terminals. These voltage values establish the upper and lower limits of the analog input to produce a full-scale and zero-scale reading, respectively. These voltages and the analog input should not exceed the positive supply or be lower than ground consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF+ terminal voltage and at zero when the input signal is equal to or lower than REF- terminal voltage.



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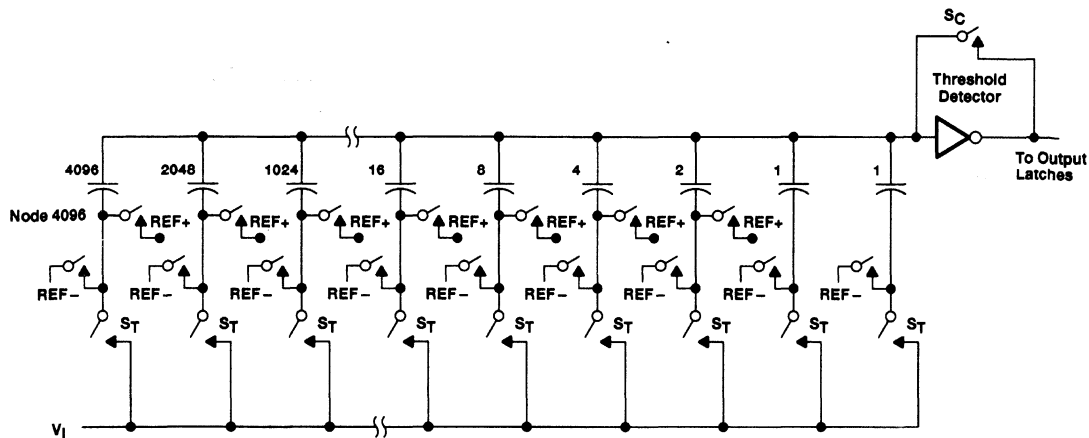


Figure 1. Simplified Model of the Successive-Approximation System

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	-0.5 V to 6.5 V
Input voltage range, V_I (any input)	-0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O	-0.3 V to $V_{CC} + 0.3$ V
Positive reference voltage, V_{ref+}	$V_{CC} + 0.1$ V
Negative reference voltage, V_{ref-}	-0.1 V
Peak input current, I_I (any input)	± 20 mA
Peak total input current, I_I (all inputs)	± 30 mA
Operating free-air temperature range, T_A : TLC2543C	0°C to 70°C
	TLC2543I	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the GND terminal with REF- and GND wired together (unless otherwise noted).

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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		4.5	5	5.5	V
Positive reference voltage, V_{ref+} (see Note 2)		V_{CC}			V
Negative reference voltage, V_{ref-} (see Note 2)		0			V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)		2.5	V_{CC}	$V_{CC} + 0.1$	V
Analog input voltage (see Note 2)		0			V_{CC}
High-level control input voltage, V_{IH}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$	2			V
Low-level control input voltage, V_{IL}	$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$				0.8
Clock frequency at I/O CLOCK		0			4.1
Setup time, address bits at DATA INPUT before I/O CLOCK \uparrow , $t_{su(A)}$ (see Figure 5)		100			ns
Hold time, address bits after I/O CLOCK \uparrow , $t_h(A)$ (see Figure 5)		0			ns
Hold time, \overline{CS} low after last I/O CLOCK \downarrow , $t_h(CS)$ (see Figure 6)		0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su}(CS)$ (see Note 3 and Figure 6)		1.425			μs
Pulse duration, I/O CLOCK high, $t_{wH}(I/O)$		120			ns
Pulse duration, I/O CLOCK low, $t_{wL}(I/O)$		120			ns
Transition time, I/O CLOCK, $t_t(I/O)$ (see Note 4 and Figure 7)					1
Transition time, DATA INPUT and \overline{CS} , $t_t(CS)$					10
Operating free-air temperature, T_A	TLC2543C	0			70
	TLC2543I	-40			85

- NOTES: 2. Analog input voltages greater than that applied to $REF+$ convert as all ones (11111111111), while input voltages less than that applied to $REF-$ convert as all zeros (000000000000).
3. To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for a setup time after $\overline{CS}\downarrow$ before responding to control input signals. No attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.
4. This is the time required for the clock input signal to fall from V_{IHmin} to V_{ILmax} or to rise from V_{ILmax} to V_{IHmin} . In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 1 μs for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.

electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.5 \text{ V to } 5.5 \text{ V}$, I/O CLOCK frequency = 4.1 MHz (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP \dagger	MAX	UNIT
V_{OH}	High-level output voltage	$V_{CC} = 4.5 \text{ V}$,	$I_{OH} = -1.6 \text{ mA}$	2.4		$V_{CC} - 0.1$	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$,	$I_{OH} = -20 \mu\text{A}$				
V_{OL}	Low-level output voltage	$V_{CC} = 4.5 \text{ V}$,	$I_{OL} = 1.6 \text{ mA}$			0.4	V
		$V_{CC} = 4.5 \text{ V to } 5.5 \text{ V}$,	$I_{OL} = 20 \mu\text{A}$			0.1	
I_{OZ}	Off-state (high-impedance-state) output current	$V_O = V_{CC}$,	\overline{CS} at V_{CC}	1		2.5	μA
		$V_O = 0$,	\overline{CS} at V_{CC}	1		-2.5	
I_{IH}	High-level input current	$V_I = V_{CC}$		1		2.5	μA
I_{IL}	Low-level input current	$V_I = 0$		1		-2.5	μA
I_{CC}	Operating supply current	\overline{CS} at 0 V		1		2.5	mA
$I_{CC(PD)}$	Power-down current	For all digital inputs, $0 \leq V_I \leq 0.5 \text{ V}$ or $V_I \geq V_{CC} - 0.5 \text{ V}$		4		25	μA
		Selected channel leakage current		Selected channel at V_{CC} , Unselected channel at 0 V		1	
		Selected channel at 0 V, Unselected channel at V_{CC}				-1	
Maximum static analog reference current into $REF+$		$V_{ref+} = V_{CC}$,	$V_{ref-} = \text{GND}$	1		2.5	μA
C_i	Input capacitance	Analog inputs		30		60	pF
		Control inputs		5		15	

\dagger All typical values are at $V_{CC} = 5 \text{ V}$, $T_A = 25^\circ\text{C}$.



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operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 4.5 \text{ V to } 5.5 \text{ V}$, I/O CLOCK frequency = 4.1 MHz

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
E_L	Linearity error (see Note 5)	See Figure 2			±1	LSB
E_D	Differential linearity error	See Figure 2			±1	LSB
E_O	Offset error (see Note 6)	See Note 2 and Figure 2			±1.5	LSB
E_G	Gain error (see Note 6)	See Note 2 and Figure 2			±1	LSB
E_T	Total unadjusted error (see Note 7)				±1.75	LSB
Self-test output code (see Table 3 and Note 8)		DATA INPUT = 1011		2048		
		DATA INPUT = 1100		0		
		DATA INPUT = 1101		4095		
t_{conv}	Conversion time	See Figures 10–15		8	10	μs
t_c	Total cycle time (access, sample, and conversion)	See Figures 10–15 and Note 9			10 + total I/O CLOCK periods + $t_d(I/O-EOC)$	μs
t_{acq}	Channel acquisition time (sample)	See Figures 10–15 and Note 9	4		12	I/O CLOCK periods
t_v	Valid time, DATA OUT remains valid after I/O CLOCK↓	See Figure 7	10			ns
$t_d(I/O-DATA)$	Delay time, I/O CLOCK↓ to DATA OUT valid	See Figure 7			150	ns
$t_d(I/O-EOC)$	Delay time, last I/O CLOCK↓ to EOC↓	See Figure 8		1.5	2.2	μs
$t_d(EOC-DATA)$	Delay time, EOC↑ to DATA OUT (MSB/LSB)	See Figure 9			100	ns
t_{PZH}, t_{PZL}	Enable time, \overline{CS} ↓ to DATA OUT (MSB/LSB driven)	See Figure 4		0.7	1.3	μs
t_{PHZ}, t_{PLZ}	Disable time, \overline{CS} ↑ to DATA OUT (high impedance)	See Figure 4		70	150	ns
$t_r(EOC)$	Rise time, EOC	See Figure 9		15	50	ns
$t_f(EOC)$	Fall time, EOC	See Figure 8		15	50	ns
$t_r(\text{bus})$	Rise time, data bus	See Figure 7		15	50	ns
$t_f(\text{bus})$	Fall time, data bus	See Figure 7		15	50	ns
$t_d(I/O-CS)$	Delay time, last I/O CLOCK↓ to \overline{CS} ↓ to abort conversion (see Note 10)				5	μs

† All typical values are at $T_A = 25^\circ\text{C}$.

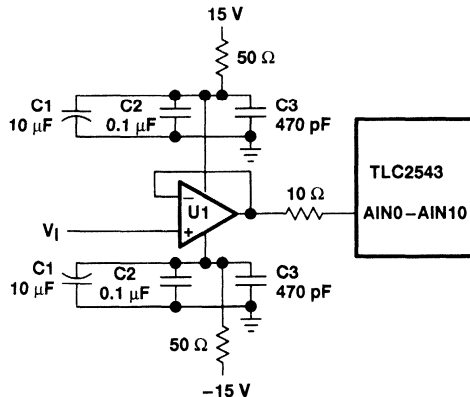
NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (11111111111), while input voltages less than that applied to REF- convert as all zeros (00000000000).

5. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
6. Gain error is the difference between the actual midstep value and the nominal midstep value in the transfer diagram at the specified gain point after the offset error has been adjusted to zero. Offset error is the difference between the actual midstep value and the nominal midstep value at the offset point.
7. Total unadjusted error comprises linearity, zero-scale, and full-scale errors.
8. Both the input address and the output codes are expressed in positive logic.
9. I/O CLOCK period = 1/(I/O CLOCK frequency) (see Figure 7).
10. Any transitions of \overline{CS} are recognized as valid only if the level is maintained for a setup time. \overline{CS} must be taken low at $\leq 5 \mu\text{s}$ of the tenth I/O CLOCK falling edge to ensure a conversion is aborted. Between 5 μs and 10 μs, the result is uncertain as to whether the conversion is aborted or the conversion results are valid.



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PARAMETER MEASUREMENT INFORMATION



LOCATION	DESCRIPTION	PART NUMBER
U1	OP27	—
C1	10-μF 35-V tantalum capacitor	—
C2	0.1-μF ceramic NPO SMD capacitor	AVX 12105C104KA105 or equivalent
C3	470-pF porcelain Hi-Q SMD capacitor	Johanson 201S420471JG4L or equivalent

Figure 2. Analog Input Buffer to Analog Inputs AIN0–AIN10

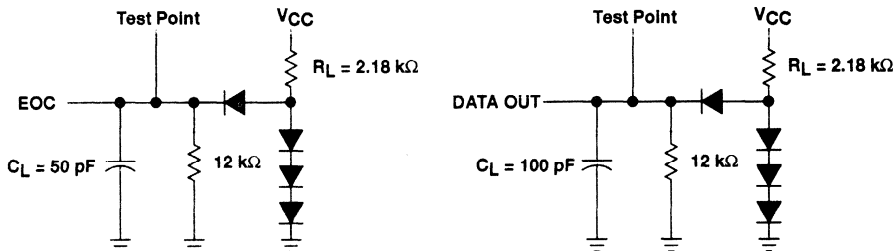


Figure 3. Load Circuits

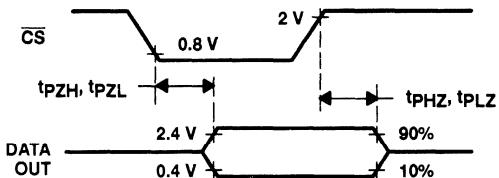


Figure 4. DATA OUT to Hi-Z Voltage Waveforms

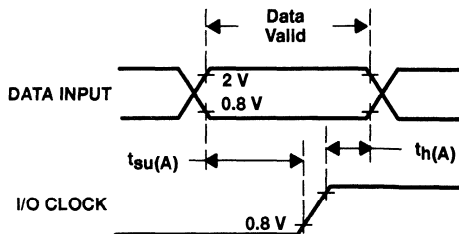


Figure 5. DATA INPUT and I/O CLOCK Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION

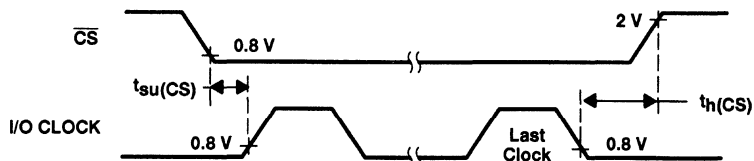


Figure 6. \overline{CS} and I/O CLOCK Voltage Waveforms†

† To ensure full conversion accuracy, it is recommended that no input signal change occurs while a conversion is ongoing.

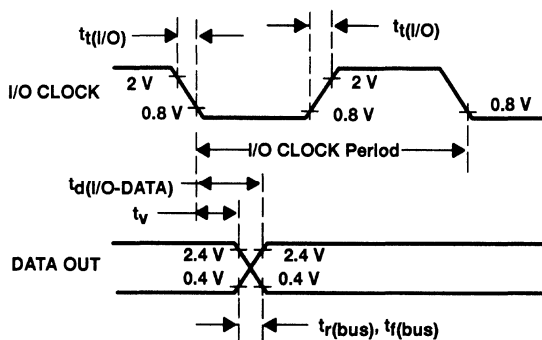


Figure 7. I/O CLOCK and DATA OUT Voltage Waveforms

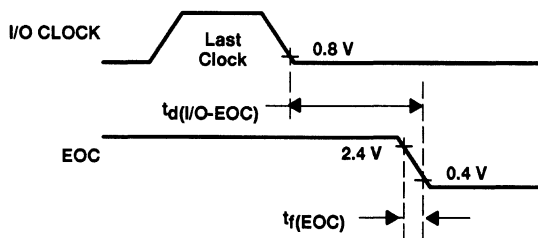


Figure 8. I/O CLOCK and EOC Voltage Waveforms

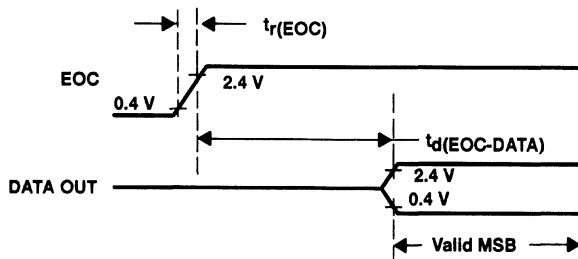


Figure 9. EOC and DATA OUT Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION

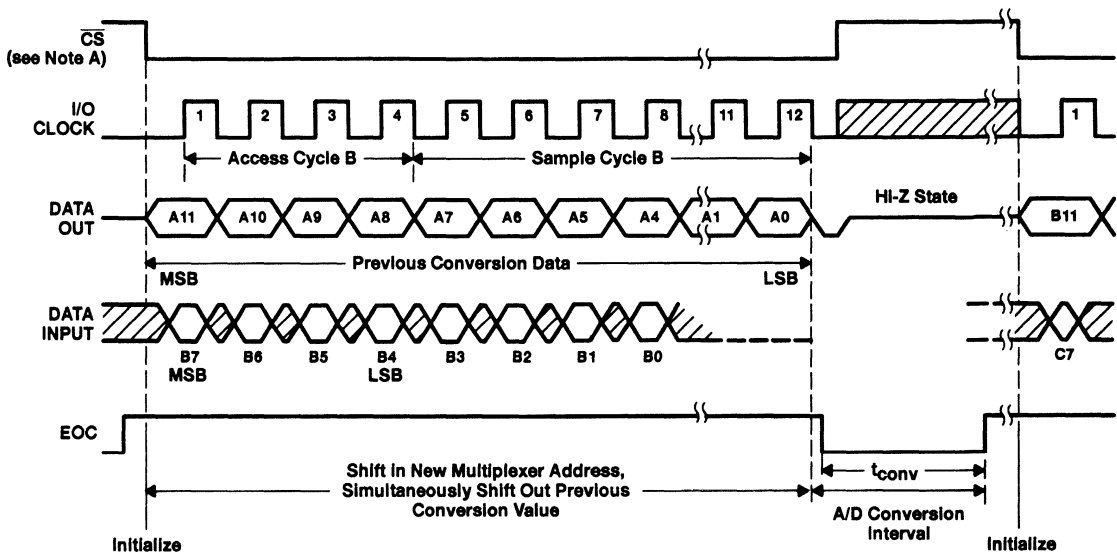


Figure 10. Timing for 12-Clock Transfer Using \overline{CS} With MSB First

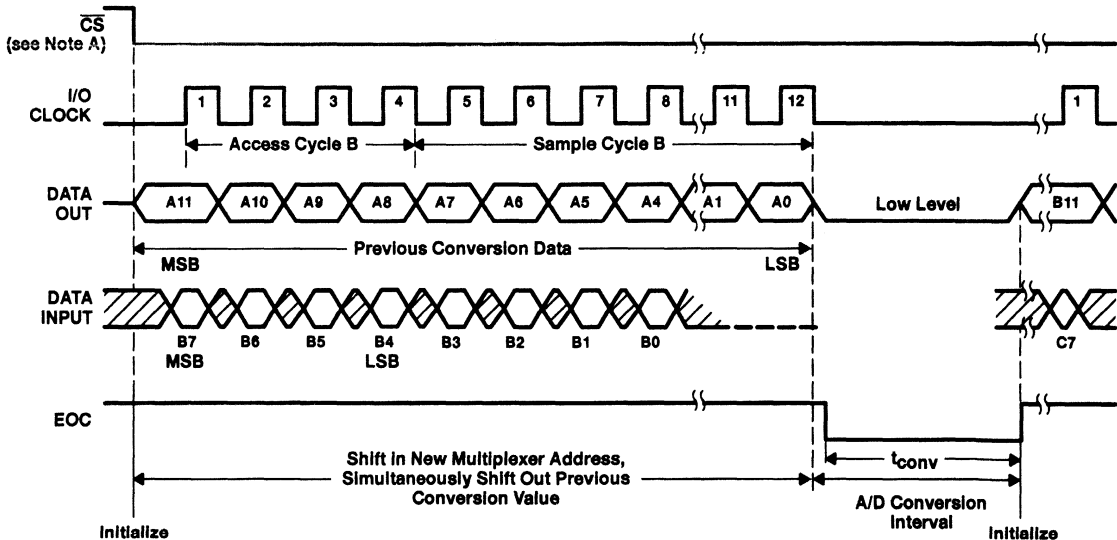


Figure 11. Timing for 12-Clock Transfer Not Using \overline{CS} With MSB First

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time after \overline{CS} before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

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PARAMETER MEASUREMENT INFORMATION

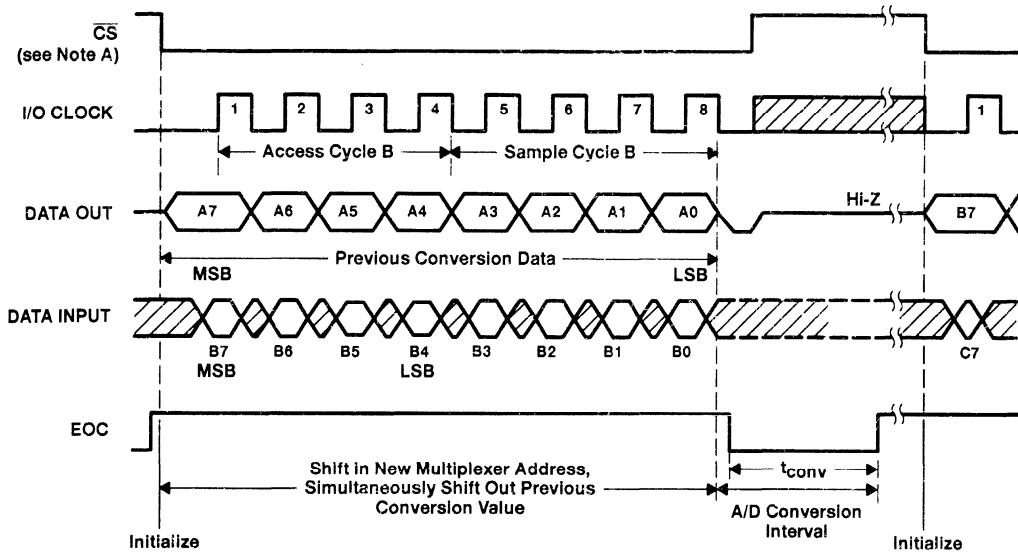


Figure 12. Timing for 8-Clock Transfer Using $\overline{\text{CS}}$ With MSB First

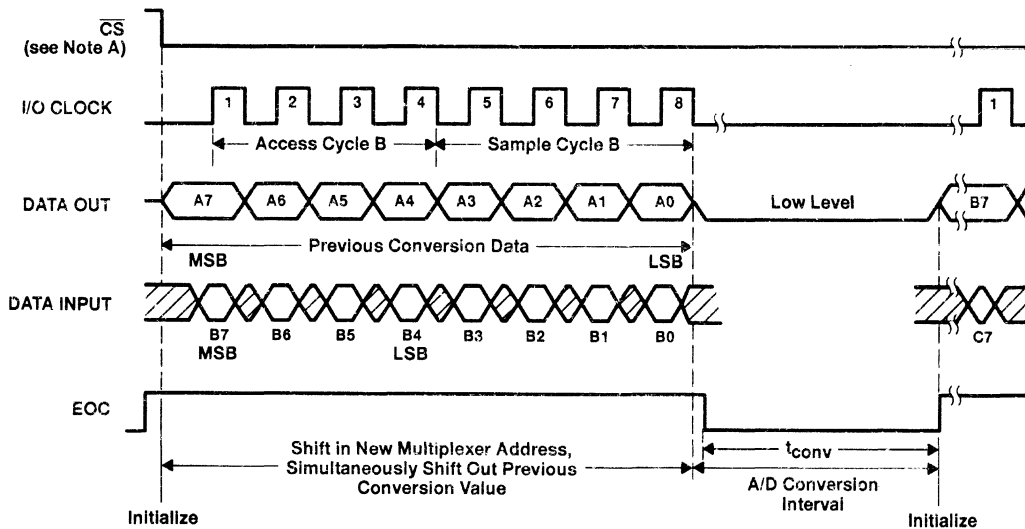


Figure 13. Timing for 8-Clock Transfer Not Using $\overline{\text{CS}}$ With MSB First

NOTE A: To minimize errors caused by noise at $\overline{\text{CS}}$, the internal circuitry waits for a setup time after $\overline{\text{CS}}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum $\overline{\text{CS}}$ setup time has elapsed.



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PARAMETER MEASUREMENT INFORMATION

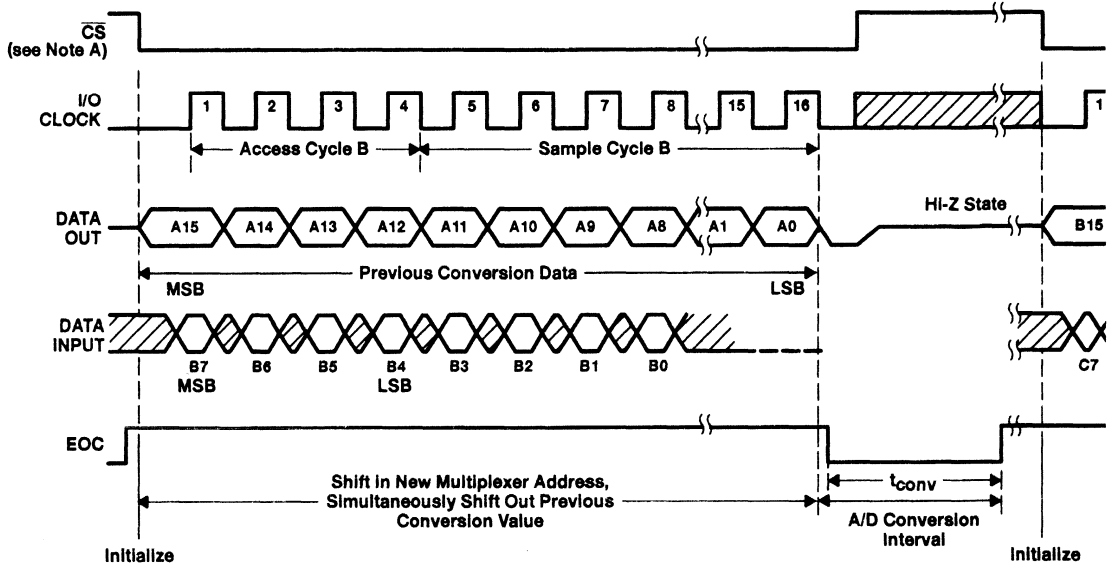


Figure 14. Timing for 16-Clock Transfer Using \overline{CS} With MSB First

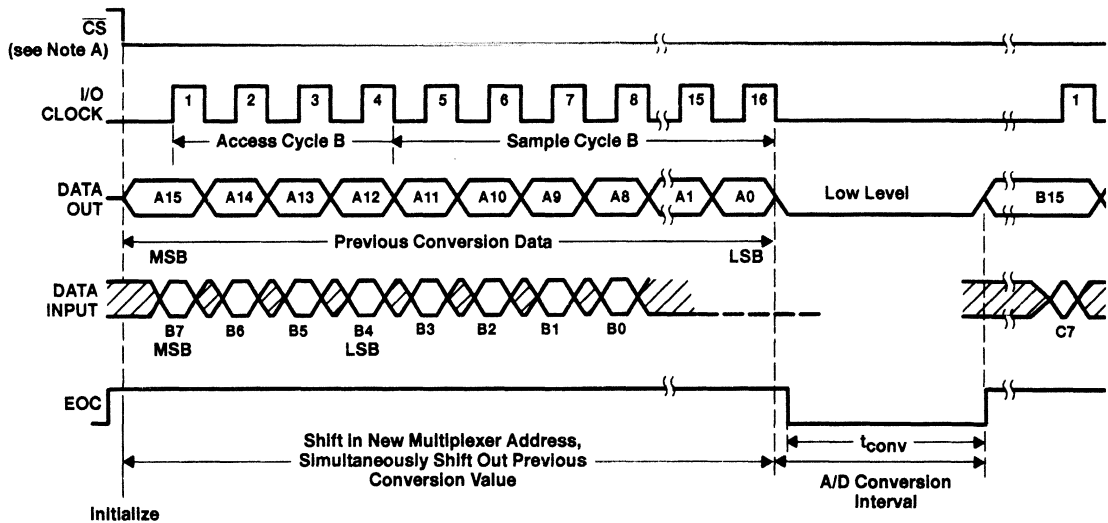


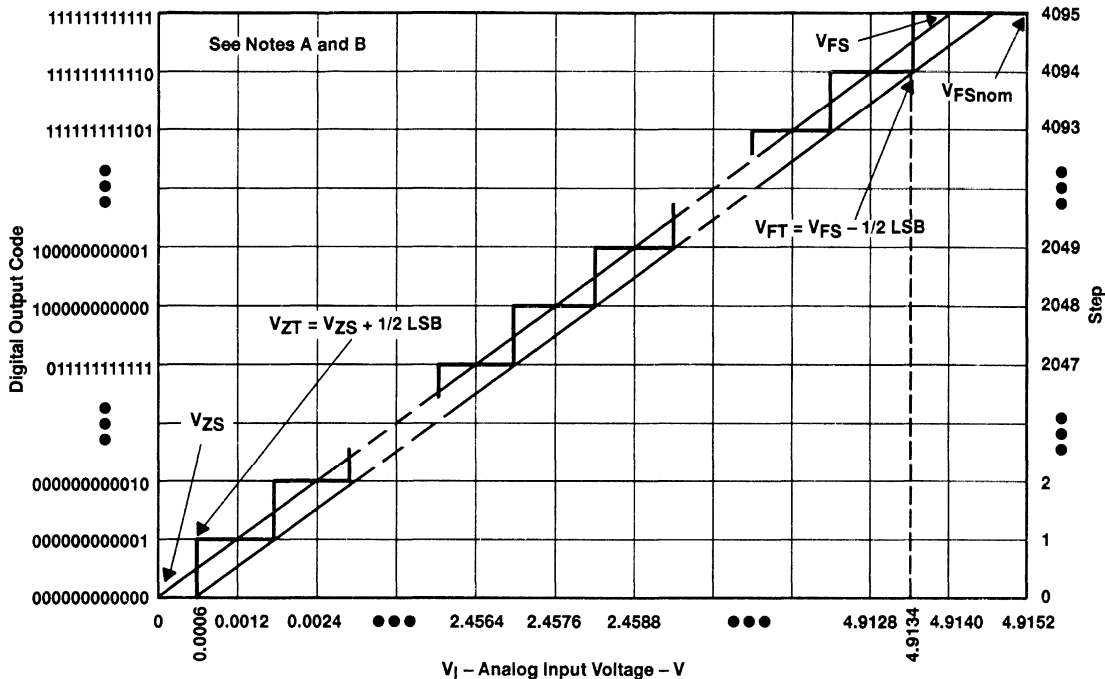
Figure 15. Timing for 16-Clock Transfer Not Using \overline{CS} With MSB First

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

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APPLICATION INFORMATION



- NOTES: A. This curve is based on the assumption that V_{ref+} and V_{ref-} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 0.0006 V and the transition to full scale (V_{FT}) is 4.9134 V. 1 LSB = 1.2 mV.
 B. The full-scale value (V_{FS}) is the step whose nominal midstep value has the highest absolute value. The zero-scale value (V_{ZS}) is the step whose nominal midstep value equals zero.

Figure 16. Ideal Conversion Characteristics

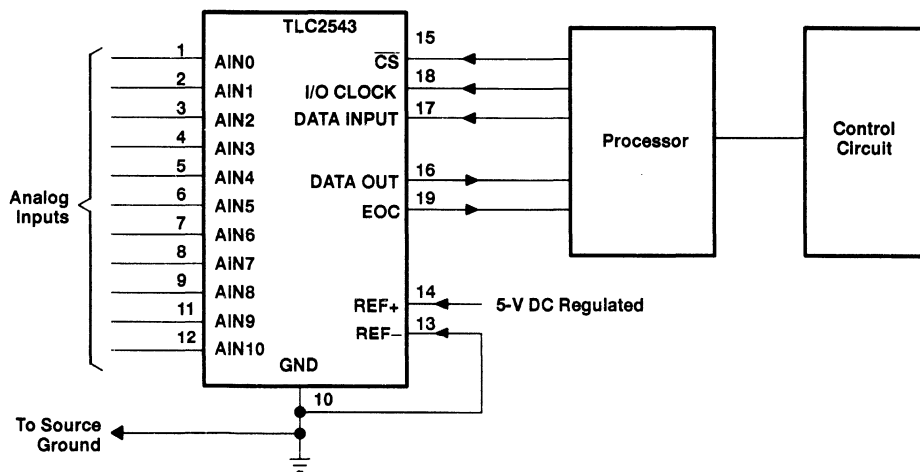


Figure 17. Serial Interface

APPLICATIONS INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 18, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S / 8192) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S / 8192) = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (3)$$

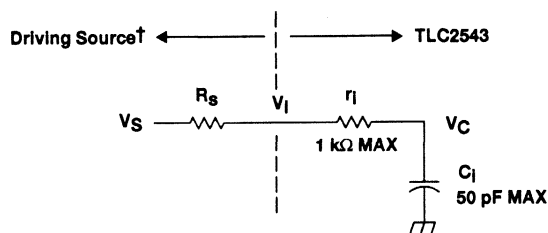
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(8192) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(8192) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at AIN
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 18. Equivalent Input Circuit Including the Driving Source

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features

- **8-Bit Resolution**
- **Linearity Error**
 ± 0.75 LSB Max (25°C)
 ± 1 LSB Max (–20°C to 75°C)
- **Differential Linearity Error**
 ± 0.5 LSB (25°C)
 ± 0.75 LSB Max (–20°C to 75°C)
- **Maximum Conversion Rate**
20 Mega-Samples per Second (MSPS) Min
- **5-V Single-Supply Operation**
- **Low Power Consumption . . . 90 mW Typ**
- **Interchangeable With Sony CXD1175**

applications

- Digital TV
- Medical Imaging
- Video Conferencing
- High-Speed Data Conversion
- QAM Demodulators

description

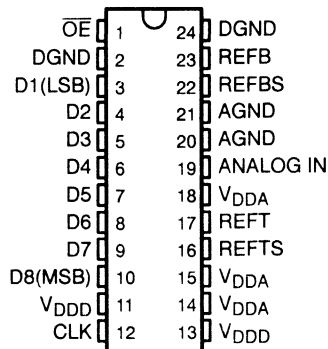
The TLC5510 is a CMOS, 8-bit, 20 MSPS analog-to-digital converter (ADC) that utilizes a semiflash architecture. The TLC5510 operates with a single 5 V supply and consumes only 100 mW of power typically. Also included is an internal sample and hold circuit, parallel outputs with high impedance mode, and internal reference resistors.

The semiflash architecture reduces power consumption and die size compared to flash converters. By implementing the conversion in a 2-step process, the number of comparators is significantly reduced. The latency of the data upon conversion is 2.5 clocks.

The internal reference resistors can create a standard, 2-V, full-scale conversion range using V_{DDA} . Only external jumpers are required to implement this option. This reduces the need for external references or resistors. Differential linearity is 0.5 LSB at 25°C and a maximum of 0.75 LSB over the full operating temperature range. Dynamic characteristics are specified with a differential gain of 1% and differential phase of 0.7%.

The TLC5510 is characterized for operation from –20°C to 75°C.

NS PACKAGE† (TOP VIEW)



† Available in tape and reel only and ordered as the TLC5510INSLE.

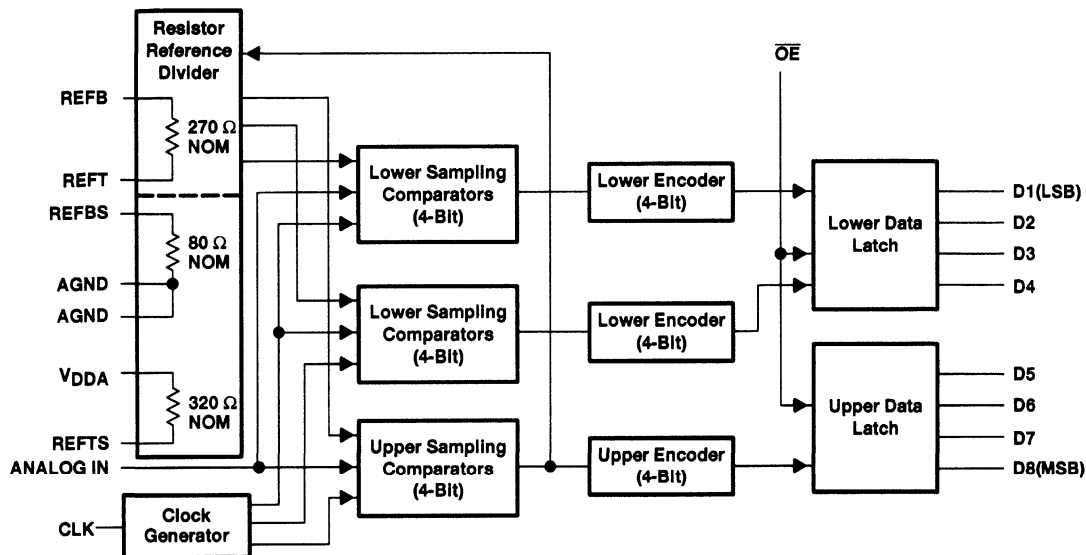
AVAILABLE OPTIONS

TA	NS PACKAGE (TAPE AND REEL ONLY)
–20°C to 75°C	TLC5510INSLE

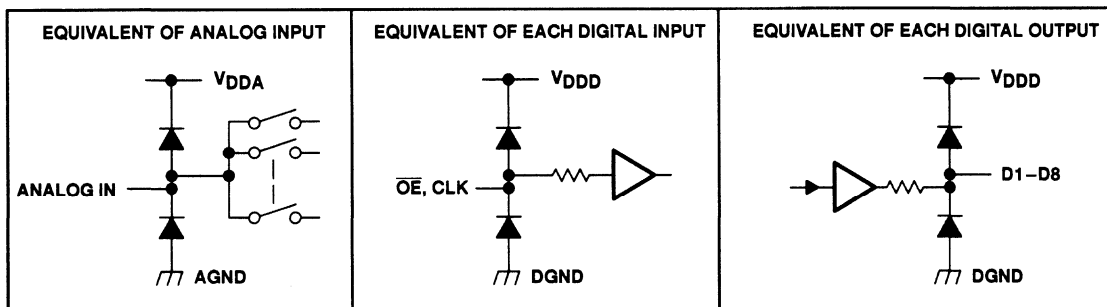
TLC5510 8-BIT HIGH-SPEED ANALOG-TO-DIGITAL CONVERTER

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functional block diagram



schematics of inputs and outputs



TLC5510

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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AGND	20, 21		Analog ground
ANALOG IN	19	I	Analog input
CLK	12	I	Clock in
DGND	2, 24		Digital ground
D1–D8	3–10	O	Digital data out. D1:LSB, D8:MSB
\overline{OE}	1	I	Output enable. When $\overline{OE} = L$, data is enabled. When $\overline{OE} = H$, D1–D8 is in high impedance state.
V _{DDA}	14, 15, 18		Analog V _{DD}
V _{DDD}	11, 13		Digital V _{DD}
REFB	23	I	Reference voltage in (bottom)
REFBS	22		Reference voltage (bottom). When using the internal voltage divider to generate a nominal 2-V reference, this terminal is shorted to the REFB terminal (see Figure 2).
REFT	17	I	Reference voltage in (top)
REFTS	16		Reference voltage (top). When using the internal voltage divider to generate a nominal 2-V reference, this terminal is shorted to the REFT terminal (see Figure 2).

absolute maximum ratings†

Supply voltage, V _{DDA} , V _{DDD}	7 V
Reference voltage input range, V _{ref(T)} , V _{ref(B)} , V _{ref(BS)} , V _{ref(TS)}	AGND to V _{DDA}
Analog input voltage range, V _{I(ANLG)}	AGND to V _{DDA}
Digital input voltage range, V _{I(DGTL)}	DGND to V _{DDD}
Digital output voltage range, V _{O(DGTL)}	DGND to V _{DDD}
Operating free-air temperature range, T _A	–20°C to 75°C
Storage temperature range, T _{stg}	–55°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT	
Supply voltage	V _{DDA} –AGND	4.75	5	5.25	V
	V _{DDD} –AGND	4.75	5	5.25	
	AGND–DGND	–100	0	100	mV
Reference input voltage (top), V _{ref(T)}	V _{ref(B)} +2	V _{ref(B)} +2	2.7	V	
Reference input voltage (bottom), V _{ref(B)}	0	0.6	V _{ref(T)} –2	V	
Analog input voltage range, V _{I(ANLG)} (see Note 1)	V _{ref(B)}		V _{ref(T)}	V	
High-level input voltage, V _{IH}	4			V	
Low-level input voltage, V _{IL}			1	V	
Pulse duration, clock high, t _{w(H)}	25			ns	
Pulse duration, clock low, t _{w(L)}	25			ns	

NOTE 1: REFT – REFB ≥ 2.4 V maximum



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electrical characteristics at $V_{DD} = 5\text{ V}$, $V_{ref(T)} = 2.5\text{ V}$, $V_{ref(B)} = 0.5\text{ V}$, $f_{conv} = 20\text{ MSPS}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS†		MIN	TYP	MAX	UNIT
E _L	Linearity error	f _{conv} = 20 MSPS, V _I = 0.5 V to 2.5 V	T _A = 25°C		±0.4	±0.75	LSB
			T _A = -20°C to 75°C			±1	
E _D	Linearity error, differential		T _A = 25°C		±0.3	±0.5	
		T _A = -20°C to 75°C			±0.75		
Self bias (1)		Short REFB to REFBS, Short REFT to REFTS		0.57	0.61	0.65	V
Self bias (2)				1.9	2.02	2.15	
Self bias (3)		Short REFB to AGND, Short REFT to REFTS		2.18	2.29	2.4	
I _{ref}	Reference voltage current	V _{ref(T)} - V _{ref(B)} = 2 V		5.2	7.5	10.5	mA
R _{ref}	Reference voltage resistor	Between REFT and REFB terminals		190	270	350	Ω
C _i	Analog input capacitance	V _I (ANLG) = 1.5 V + 0.07 V _{rms}			16		pF
E _{ZS}	Zero-scale error	V _{ref} = REFT - REFB = 2 V		-18	-43	-68	mV
E _{FS}	Full-scale error			-20	0	20	
I _{IH}	High-level input current	V _{DD} = MAX,	V _{IH} = V _{DD}			5	μA
I _{IL}	Low-level input current	V _{DD} = MAX,	V _{IL} = 0 V			5	
I _{OH}	High-level output current	\overline{OE} = GND,	V _{DD} = MIN, V _{OH} = V _{DD} - 0.5 V	-1.5			mA
I _{OL}	Low-level output current	\overline{OE} = GND,	V _{DD} = MIN, V _{OL} = 0.4 V	2.5			
I _{OZH}	High-level high-impedance-state output leakage current	\overline{OE} = V _{DD} ,	V _{DD} = MAX V _{OH} = V _{DD}			16	μA
I _{OZL}	Low-level high-impedance-state output leakage current	\overline{OE} = V _{DD} ,	V _{DD} = MIN V _{OL} = 0 V			16	
I _{DD}	Supply current	f _s = 20 MSPS,	National Television System Committee (NTSC) ramp wave input		18	27	mA

† Conditions marked MIN or MAX are as stated in recommended operating conditions.

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operating characteristics at $V_{DD} = 5\text{ V}$, $V_{RT} = 2.5\text{ V}$, $V_{RB} = 0.5\text{ V}$, $f_s = 20\text{ MSPS}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{conv} Maximum conversion rate	$V_I(\text{ANLG}) = 0.5\text{ V} - 2.5\text{ V}$, $f_I = 1\text{-kHz ramp wave form}$	20			MSPS
BW Analog input bandwidth	$A_t - 1\text{ dB}$		14		MHz
t_{dd} Digital output delay time	$C_L \leq 10\text{ pF}$ (see Note 2)		18	30	ns
Differential gain	NTSC 40 Institute of Radio Engineers (IRE) modulation wave, $f_{conv} = 14.3\text{ MSPS}$		1%		
Differential phase			0.7		degrees
t_{AJ} Aperture jitter time			30		ps
$t_{d(s)}$ Sampling delay time			4		ns

NOTE 2: C_L includes probe and jig capacitance

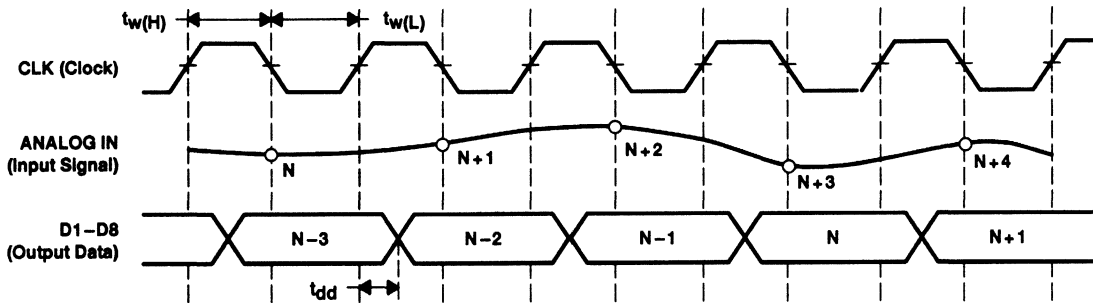


Figure 1. I/O Timing Diagram

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APPLICATION INFORMATION

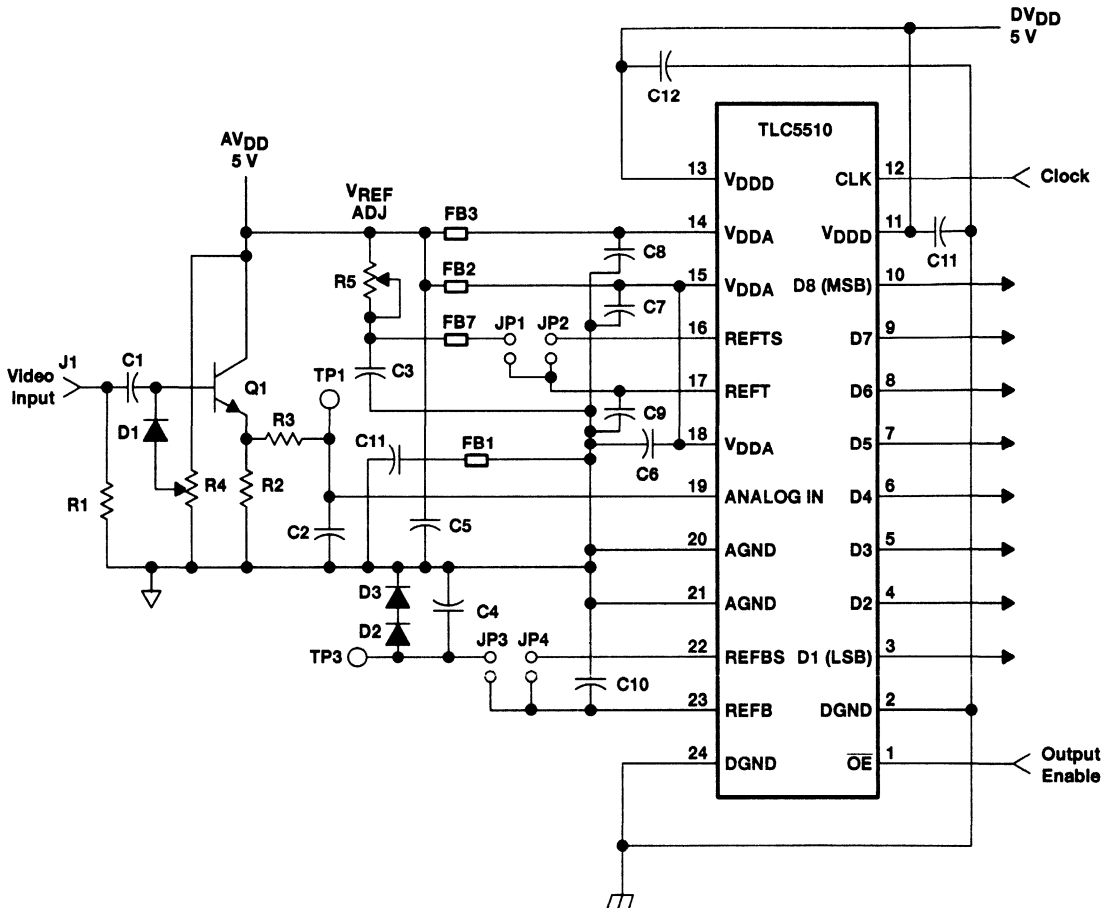
The following notes are design recommendations that should be used with the TLC5510.

- External analog and digital circuitry should be physically separated and shielded as much as possible to reduce system noise.
- RF breadboarding or printed-circuit-board (PCB) techniques should be used throughout the evaluation and production process. Breadboards should be copper clad for bench evaluation.
- Since AGND and DGND are not connected internally, these terminals need to be connected externally. With breadboards, these ground lines should be connected through separate leads with correct supply bypassing. A good method to use is separate twisted-pair cables for the supply lines to minimize noise pickup. An analog and digital ground plane should be used on PCB layouts.
- V_{DDA} to AGND and V_{DDD} to DGND should be decoupled with 1- μ F and 0.01- μ F capacitors, respectively, and placed as close as possible to the affected device terminals. A ceramic-chip capacitor is recommended for the 0.01- μ F capacitor. Care should be exercised to ensure a solid noise-free ground connection for the analog and digital grounds.
- V_{DDA} , AGND, and ANALOG IN terminals should be shielded from the higher frequency terminals, CLK and D0–D7. When possible, AGND traces should be placed on both sides of the ANALOG IN traces on the PCB for shielding.
- In testing or application of the device, the resistance of the driving source connected to the analog input should be 10 Ω or less within the analog frequency range of interest.

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APPLICATION INFORMATION



LOCATION	DESCRIPTION
C1, C3–C4, C6–C12	0.1- μ F Capacitor
C2	10-pF Capacitor
C5	47- μ F Capacitor
FB1, FB2, FB3, FB7	Ferrite Bead
Q1	2N3414 or equivalent
R1, R3	75- Ω resistor
R2	500- Ω resistor
R4	10-k Ω resistor, clamp voltage adjust
R5	300- Ω resistor, reference-voltage fine adjust

Figure 2. Application and Test Schematic

NOTE A: JP1, JP2, JP3, and JP4 allow adjustment of the reference voltage by R5 using temperature-compensating diodes D2, D3.

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PRINCIPLES OF OPERATION

functional description

The TLC5510 is a semiflash ADC featuring two lower comparator blocks of four bits each.

As shown in Figure 3, input voltage $V_I(1)$ is sampled with the falling edge of CLK1 to the upper comparators block and the lower comparators block(A), S(1). The upper comparators block finalizes the upper data UD(1) with the rising edge of CLK2, and simultaneously, the lower reference voltage generates the voltage RV(1) corresponding to the upper data. The lower comparators block (A) finalizes the lower data LD(1) with the rising edge of CLK3. UD(1) and LD(1) are combined and output as OUT(1) with the rising edge of CLK4. According to the above internal operation described, output data is delayed 2.5 clocks from the analog input voltage sampling point.

Input voltage $V_I(2)$ is sampled with the falling edge of CLK2. UD(2) is finalized with the rising edge of CLK3, and LD(2) is finalized with the rising edge of CLK4 at the lower comparators block(B). OUT(2) is output with the rising edge of CLK5.

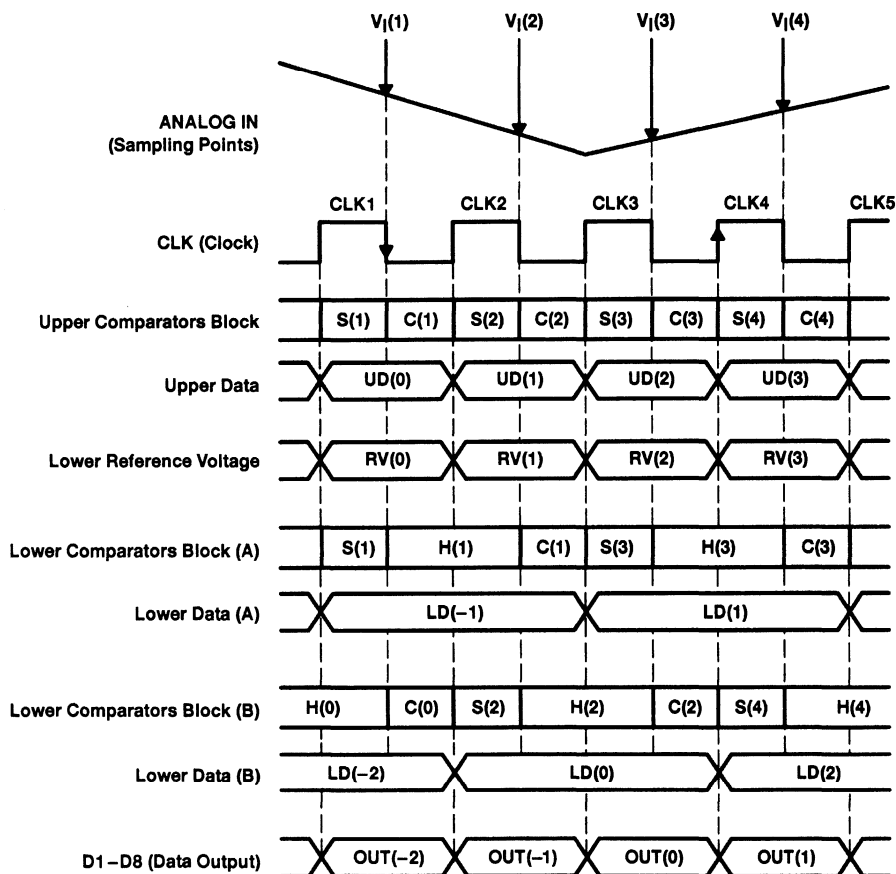


Figure 3. Internal Functional Timing Diagram

PRINCIPLES OF OPERATION

internal referencing

Three internal resistors are provided so that the device can generate an internal reference voltage. These resistors are brought out on terminals V_{DDA} , REFTS, REFT, REFB, REFBS, and AGND.

To use the internally generated reference voltage, terminal connections should be made as shown in Figure 4. This connection provides the standard video 2-V reference for the nominal digital output.

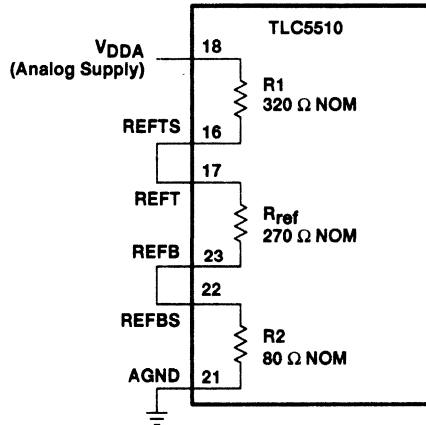


Figure 4. External Connections for Using the Internal-Reference Resistor Divider

functional operation

The TLC5510 functions as shown in Table 1.

Table 1. Functional Operation

INPUT SIGNAL VOLTAGE	STEP	DIGITAL OUTPUT CODE							
		MSB							LSB
$V_{ref(T)}$	0	1	1	1	1	1	1	1	1
•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•
•	127	1	0	0	0	0	0	0	0
•	128	0	1	1	1	1	1	1	1
•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•
$V_{ref(B)}$	255	0	0	0	0	0	0	0	0

TLC5540

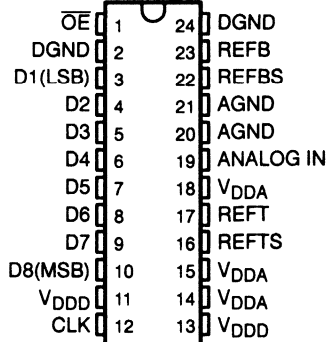
8-BIT HIGH-SPEED ANALOG-TO-DIGITAL CONVERTER

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features

- **8-Bit Resolution**
- **Linearity Error**
 - ± 0.75 LSB Max (25°C)
 - ± 1 LSB Max (–20°C to 75°C)
- **Differential Linearity Error**
 - ± 0.5 LSB (25°C)
 - ± 0.75 LSB Max (–20°C to 75°C)
- **Maximum Conversion Rate of 40 Mega-Samples per Second (MSPS) Min**
- **Internal Sample and Hold**
- **5-V Single-Supply Operation**
- **Low Power Consumption . . . 100 mW Typ**
- **Analog Input Bandwidth . . . >75 MHz Typ**

**NS PACKAGE
(TOP VIEW)**



applications

- **Quadrature Phase Shift Keying (QPSK) Demodulators**
- **Medical Imaging**
- **Charge-Coupled Device (CCD) Scanners**
- **Video Conferencing**
- **Digital Set-Top Box**
- **Digital Down Converters**
- **High-Speed Signal Processing**

AVAILABLE OPTIONS

T _A	NS PACKAGE
–20°C to 75°C	TLC5540INS

description

The TLC5540 is a CMOS, 8-bit, 40 MSPS analog-to-digital converter (ADC) that utilizes a semiflash architecture. The TLC5540 operates with a single 5 V supply and consumes only 100 mW of power typically. Also included is an internal sample and hold circuit, parallel outputs with high impedance mode and internal reference resistors.

The TLC5540 has a wide analog-input bandwidth typically greater than 75 MHz. This feature allows use of the ADC in undersampling applications such as digital down converters and allows the elimination of expensive RF components.

The semiflash architecture reduces power consumption and die size compared to flash converters. The conversion is implemented in a 2-step process which significantly reduces the number of comparators. The latency of the data upon conversion is 2.5 clocks.

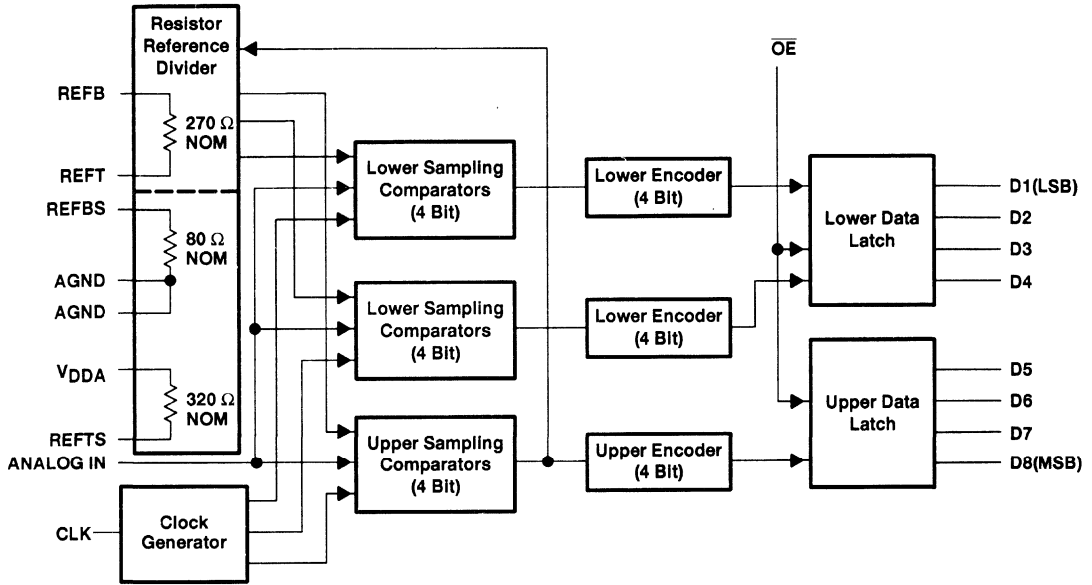
The internal reference resistors can create a standard 2-V full-scale conversion range using V_{DDA}. Only external jumpers are required to implement this option, thereby reducing the need for external references or resistors. The TLC5540 is characterized for operation from –20°C to 75°C. Differential linearity is ± 0.5 LSB at 25°C and a maximum of ± 0.75 LSB over the full operating temperature range. Dynamic characteristics are specified with a differential gain of 1% and differential phase of 0.7%.

PRODUCT PREVIEW

TLC5540 8-BIT HIGH-SPEED ANALOG-TO-DIGITAL CONVERTER

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functional block diagram



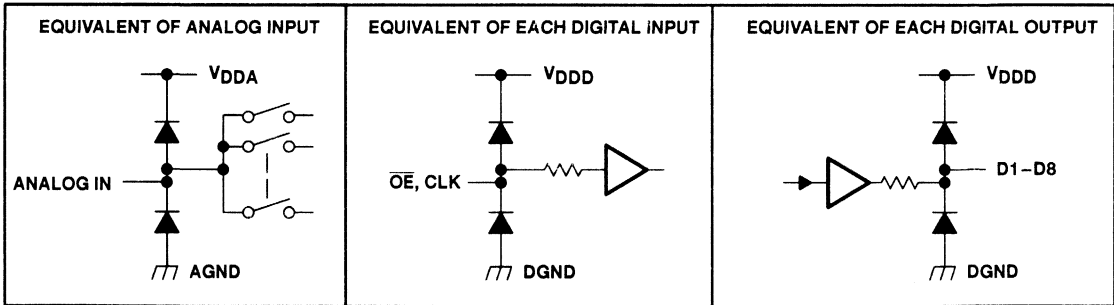
PRODUCT PREVIEW

TLC5540

8-BIT HIGH-SPEED ANALOG-TO-DIGITAL CONVERTER

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schematics of inputs and outputs



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AGND	20, 21		Analog ground
ANALOG IN	19	I	Analog input
CLK	12	I	Clock input
DGND	2, 24		Digital ground
D1–D8	3–10	O	Digital data out. D1:LSB, D8:MSB
\overline{OE}	1	I	Output enable. When $\overline{OE} = L$, data is enabled. When $\overline{OE} = H$, D1–D8 is high impedance.
VDDA	14, 15, 18		Analog VDD
VDDD	11, 13		Digital VDD
REFB	23	I	Reference voltage in (bottom)
REFBS	22		Reference voltage (bottom). When using the internal voltage divider to generate a nominal 2-V reference, this terminal is shorted to the REFBS terminal and the REFTS terminal is shorted to the REFT terminal (see Figure 3).
REFT	17	I	Reference voltage in (top)
REFTS	16		Reference voltage (top). When using the internal voltage divider to generate a nominal 2-V reference, this terminal is shorted to the REFT terminal and the REFBS terminal is shorted to the REFBS terminal (see Figure 3).

absolute maximum ratings†

Supply voltage, V_{DDA} , V_{DDD}	7 V
Reference voltage input range, $V_{ref(T)}$, $V_{ref(B)}$, $V_{ref(BS)}$, $V_{ref(TS)}$	AGND to V_{DDA}
Analog input voltage range, $V_{I(ANLG)}$	AGND to V_{DDA}
Digital input voltage range, $V_{I(DGTL)}$	DGND to V_{DDD}
Digital output voltage range, $V_{O(DGTL)}$	DGND to V_{DDD}
Operating free-air temperature range, T_A	–20°C to 75°C
Storage temperature range, T_{stg}	–55°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

PRODUCT PREVIEW

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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage	V _{DDA} – AGND	4.75	5	5.25	V
	V _{DDD} – AGND	4.75	5	5.25	
	AGND – DGND	-100	0	100	mV
Reference input voltage (top), V _{ref(T)}		V _{ref(B)} +2	V _{ref(B)} +2	2.7	V
Reference input voltage (bottom), V _{ref(B)}		0	0.6	V _{ref(T)} -2	V
Analog input voltage range, V _{I(ANLG)} (see Note 1)		V _{ref(B)}		V _{ref(T)}	V
High-level input voltage, V _{IH}		4			V
Low-level input voltage, V _{IL}		1			V
Pulse duration, clock high, t _{w(H)}		25			ns
Pulse duration, clock low, t _{w(L)}		25			ns

NOTE 1: REFT – REFB ≥ 2.4 V maximum

electrical characteristics at V_{DD} = 5 V, V_{ref(T)} = 2.5 V, V_{ref(B)} = 0.5 V, f_(sampling) = 40 MSPS, T_A = 25°C (unless otherwise noted)

PRODUCT PREVIEW

PARAMETER		TEST CONDITIONST		MIN	TYP	MAX	UNIT
E _L	Linearity error	f _(sampling) = 40 MSPS, V _I = 0.5 V to 2.5 V	T _A = 25°C		±0.4	±0.75	LSB
			T _A = -20°C to 75°C			±1	
E _D	Linearity error, differential		T _A = 25°C		±0.3	±0.5	
			T _A = -20°C to 75°C			±0.75	
Self bias (1)		Short REFB to REFB _S , Short REFT to REFT _S		0.57	0.61	0.65	V
Self bias (2)				1.9	2.02	2.15	
Self bias (3)			Short REFB to AGND, Short REFT to REFT _S		2.18	2.29	
I _{ref}	Reference-voltage current	V _{ref(T)} – V _{ref(B)} = 2 V		5.2	7.5	10.5	mA
R _{ref}	Reference-voltage resistor	Between REFT and REFB terminals		190	270	350	Ω
C _i	Analog-input capacitance	V _{I(ANLG)} = 1.5 V + 0.07 V _{rms}			16		pF
E _{ZS}	Zero-scale error	V _{ref} = REFT – REFB = 2 V		-18	-43	-68	mV
E _{FS}	Full-scale error			-20	0	20	
I _{IH}	High-level input current	V _{DD} = MAX,	V _{IH} = V _{DD}			5	μA
I _{IL}	Low-level input current	V _{DD} = MAX,	V _{IL} = 0			5	
I _{OH}	High-level output current	\overline{OE} = GND,	V _{DD} = MIN, V _{OH} = V _{DD} – 0.5 V	-1.5			mA
I _{OL}	Low-level output current	\overline{OE} = GND,	V _{DD} = MIN, V _{OL} = 0.4 V	2.5			
I _{OZH}	High-level high-impedance-state output leakage current	\overline{OE} = V _{DD} ,	V _{DD} = MAX V _{OH} = V _{DD}			16	μA
I _{OZL}	Low-level high-impedance-state output leakage current	\overline{OE} = V _{DD} ,	V _{DD} = MIN V _{OL} = 0			16	
I _{DD}	Supply current	f _(sampling) = 40 MSPS, National Television System Committee (NTSC) ramp wave input			20	30	mA

† Conditions marked MIN or MAX are as stated in recommended operating conditions.



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operating characteristics at $V_{DD} = 5V$, $V_{RT} = 2.5V$, $V_{RB} = 0.5V$, $f_{(sampling)} = 40\text{ MSPS}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
$f_{(sampling)}$ Maximum conversion rate	$V_{I(ANLG)} = 0.5V - 2.5V$, $f_I = 1\text{-kHz ramp wave form}$	40			MSPS
BW Analog-input bandwidth	$A_t - 3\text{ dB}$		>75		MHz
t_{pd} Digital-output delay time	$C_L \leq 10\text{ pF}$ (see Note 2)		18	30	ns
Differential gain	NTSC 40 Institute Radio Engineers (IRE) modulation wave, $f_{conv} = 14.3\text{ MSPS}$		1%		
Differential phase			0.7		degrees
t_{AJ} Aperture jitter time			30		ps
$t_{d(s)}$ Sampling delay time			4		ns

NOTE 2: C_L includes probe and jig capacitance

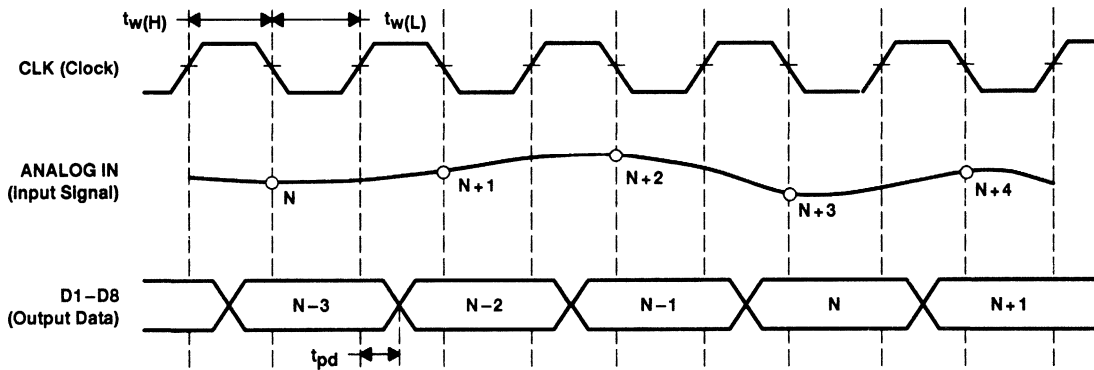


Figure 1. I/O Timing Diagram

PRODUCT PREVIEW

TLC5540 8-BIT HIGH-SPEED ANALOG-TO-DIGITAL CONVERTER

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PRINCIPLES OF OPERATION

functional description

The TLC5540 is a semiflash, analog-to-digital converter featuring two lower comparator blocks of four bits each.

As shown in Figure 2, input voltage $V_I(1)$ is sampled with the falling edge of CLK1 to the upper comparators block and the lower comparators block(A), S(1). The upper comparators block finalizes the upper data UD(1) with the rising edge of CLK2, and simultaneously, the lower reference voltage generates the voltage RV(1) corresponding to the upper data. The lower comparators block (A) finalizes the lower data LD(1) with the rising edge of CLK3. UD(1) and LD(1) are combined and output as OUT(1) with the rising edge of CLK4. According to the above internal operation described, output data is delayed 2.5 clocks from the analog input voltage sampling point.

Input voltage $V_I(2)$ is sampled with the falling edge of CLK2. UD(2) is finalized with the rising edge of CLK3, and LD(2) is finalized with the rising edge of CLK4 at the lower comparators block(B). OUT(2) is output with the rising edge of CLK5.

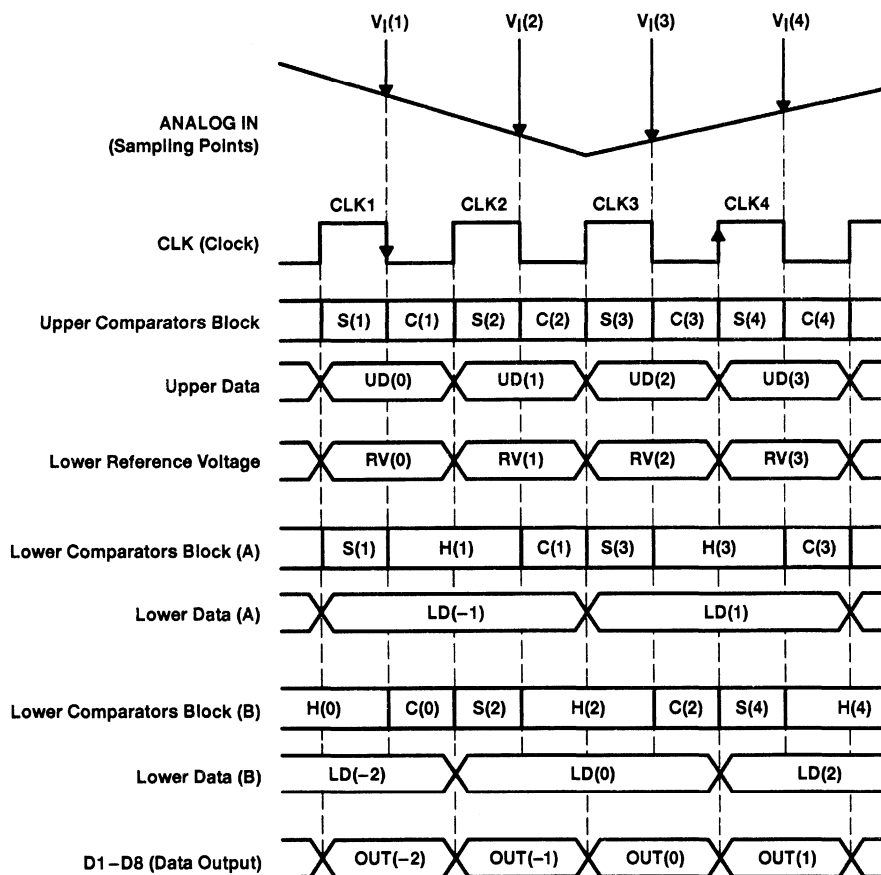


Figure 2. Internal Functional Timing Diagram

PRODUCT PREVIEW



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PRINCIPLES OF OPERATION

internal referencing

Three internal resistors allow the device to generate an internal reference voltage. These resistors are brought out on terminals V_{DDA} , REFTS, REFT, REFB, REFBS, and AGND.

To use the internally-generated reference voltage, terminal connections should be made as shown in Figure 3. This connection provides the standard video 2-V reference for the nominal digital output.

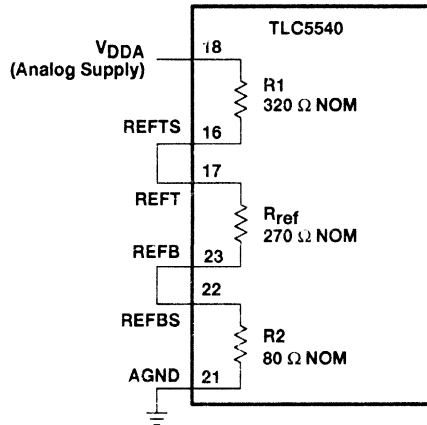


Figure 3. External Connections for Using the Internal Reference Resistor Divider

functional operation

Table 1 shows the TLC5540 functions.

Table 1. Functional Operation

INPUT SIGNAL VOLTAGE	STEP	DIGITAL OUTPUT CODE							
		MSB							LSB
$V_{ref(T)}$	0	1	1	1	1	1	1	1	1
•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•
•	127	1	0	0	0	0	0	0	0
•	128	0	1	1	1	1	1	1	1
•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•
$V_{ref(B)}$	255	0	0	0	0	0	0	0	0

PRODUCT PREVIEW

TLC5540

8-BIT HIGH-SPEED ANALOG-TO-DIGITAL CONVERTER

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APPLICATION INFORMATION

The following notes are design recommendations that should be used with the TLC5540.

- External analog and digital circuitry should be physically separated and shielded as much as possible to reduce system noise.
- RF breadboarding or printed-circuit-board (PCB) techniques should be used throughout the evaluation and production process. Breadboards should be copper clad for bench evaluation.
- Since AGND and DGND are not connected internally, these terminals need to be connected externally. With breadboards, these ground lines should be connected through separate leads with correct supply bypassing. Separate twisted-pair cables are a good method to use for the supply lines to minimize noise pickup. An analog and digital ground plane should be used on PCB layouts.
- V_{DDA} to AGND and V_{DDD} to DGND should be decoupled with 1- μ F and 0.01- μ F capacitors, respectively, placed as close as possible to the appropriate device terminals. A ceramic-chip capacitor is recommended for the 0.01- μ F capacitor. Care should be exercised to ensure a solid noise-free ground connection for the analog and digital grounds.
- V_{DDA} , AGND, and ANALOG IN terminals should be shielded from the higher frequency terminals, CLK and D0–D7. If possible, AGND traces should be placed on both sides of the ANALOG IN traces on the PCB for shielding.
- In testing or application of the device, the resistance of the driving source connected to the analog input should be 10 Ω or less within the analog frequency range of interest.

PRODUCT PREVIEW



TLC5733

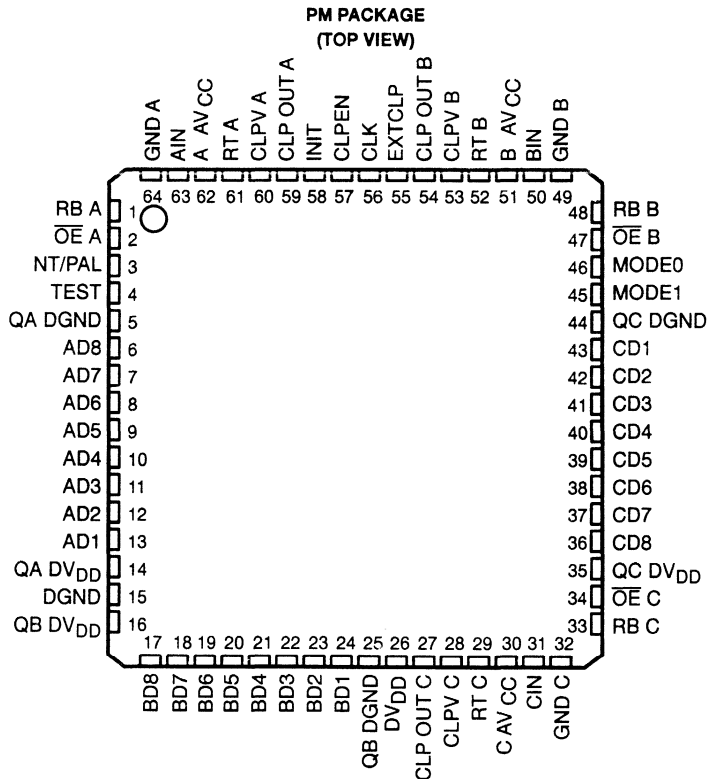
20 MSPS 3-CHANNEL ANALOG-TO-DIGITAL CONVERTER WITH HIGH-PRECISION CLAMP

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- 3-Channel CMOS ADC
- 8-Bit Resolution
- Differential Linearity Error . . . ± 0.5 LSB Max
- Linearity Error . . . ± 0.75 LSB Max
- Maximum Conversion Rate
20 Mega-Samples per Second
(MSPS) Min
- Analog Input Voltage Range
2 V_{PP} (Min)
- 64-Pin Shrink QFP Package
- Analog Input Bandwidth . . . >14 MHz
- Suitable for YUV or RGB Applications
- Digital Clamp Optimized for NTSC or PAL
YUV Component
- High Precision Clamp . . . ± 1 LSB
- Automatic Clamp Pulse Generator
- Output Data Format Multiplexer
- 5-V Single-Supply Operation
- Low Power Consumption

description

The TLC5733 is a three-channel 8-bit semiflash analog-to-digital converter (ADC) that operates from a single 5-V power supply. It converts a wide-band analog signal (such as a video signal) to digital data at sampling rates up to 20 MSPS minimum. The TLC5733 contains a feed-back type high-precision clamp circuit for each ADC channel for video (YUV) applications and a clamp pulse generator that detects COMPOSITE SYNC† pulses automatically. A clamp pulse can also be supplied externally. The output data format multiplexer selects a ratio of Y:U:V of 4:4:4, 4:1:1, or 4:2:2. For RGB applications, the 4:4:4 output format without clamp function can be used. The TLC5733 is characterized for operation from -20°C to 75°C .



† COMPOSITE SYNC refers to the externally generated synchronizing signal that is a combination of vertical and horizontal sync information used in display and TV systems.

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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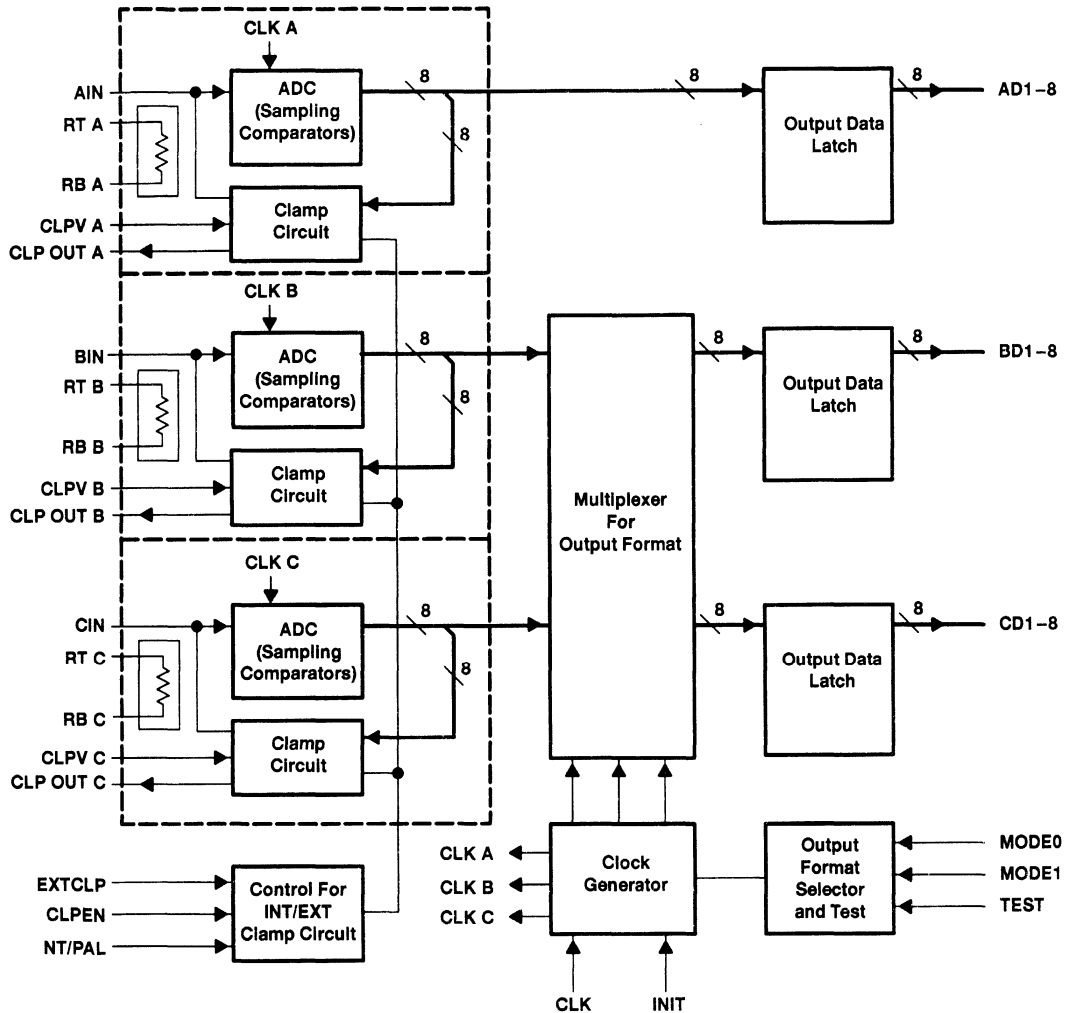
TLC5733
20 MSPS 3-CHANNEL ANALOG-TO-DIGITAL CONVERTER
WITH HIGH-PRECISION CLAMP

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AVAILABLE OPTIONS

T _A	PACKAGE
	-20°C to 75°C

functional block diagram



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WITH HIGH-PRECISION CLAMP
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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
A AV _{CC}	62	I	Analog V _{CC} of ADC A
AD8–AD1	6–13	O	Data output of ADC A (LSB: AD1, MSB:AD8)
AIN	63	I	Analog input of ADC A
B AV _{CC}	51	I	Analog V _{CC} of ADC B
BD8–BD1	17–24	O	Data output of ADC B (LSB: BD1, MSB:BD8)
BIN	50	I	Analog input of ADC B
C AV _{CC}	30	I	Analog V _{CC} of ADC C
CD8–CD1	36–43	O	Data output of ADC C (LSB:CD1, MSB: CD8) When MODE0 = L, MODE1 = L, CD8 outputs MSB flag of BD8–BD5 When MODE0 = L, MODE1 = L, CD7 outputs MSB flag of BD8–BD5 When MODE0 = L, MODE1 = H, CD8 outputs B channel flag of CD8–BD1 When MODE0 = L, MODE1 = H, CD8 outputs B channel flag of CD8–BD1
CIN	31	I	Analog input of ADC C
CLK	56	I	Clock input. The clock frequency is normally 4 fsc for most video systems (see Table 3). The nominal clock frequency is 14.31818 MHz for NTSC and 17.745 MHz for PAL.
CLPEN	57	I	Clamp enable. When using an internal clamp pulse, CLPEN should be high. When using an external clamp pulse, CLPEN should be low.
CLP OUT A	59	O	Clamping bias current of ADC A. A resistor-capacitor combination is used to set the clamp timing.
CLP OUT B	54	O	Clamping bias current of ADC B. A resistor-capacitor combination is used to set the clamp timing.
CLP OUT C	27	O	Clamping bias current of ADC C. A resistor-capacitor combination is used to set the clamp timing.
CLPV A	60	O	Clamping level of ADC A. A capacitor is connected to CLPV A to set the clamp timing. The clamp level at this terminal is connected to an output code of 16 (0010000).
CLPV B	53	O	Clamping level of ADC B. A capacitor is connected to CLPV B to set the clamp timing. The clamp level at this terminal is connected to an output code of 128 (1000000).
CLPV C	28	O	Clamping level of ADC C. A capacitor is connected to CLPV C to set the clamp timing. The clamp level at this terminal is connected to an output code of 128 (1000000).
DGND	15	I	Digital ground
DV _{DD}	26	I	Digital V _{DD}
EXTCLP	55	I	External clamp pulse input. When this terminal is low and CLPEN is low, the internal clamp circuit cannot be used.
GND A	64	I	Ground of ADC A
GND B	49	I	Ground of ADC B
GND C	32	I	Ground of ADC C
INIT	58	I	Output initialized. The output data is synchronous when INIT is taken high from low. This control terminal allows the external system to initialize the TLC5733 data conversion cycle. It is usually used upon power up or system reset.
MODE0	46	I	Output format mode selector 0
MODE1	45	I	Output format mode selector 1
NT/PAL	3	I	NTSC/PAL control. The NTSC/PAL terminal should be: NTSC = low level, PAL = high level.
OE A	2	I	Output enable of ADC A
OE B	47	I	Output enable of ADC B
OE C	34	I	Output enable of ADC C
QA DGND	5	I	Digital ground for output port of ADC A
QA DV _{DD}	14	I	Digital V _{DD} for output of ADC A
QB DGND	25	I	Digital ground for output of ADC B
QB DV _{DD}	16	I	Digital V _{DD} for output of ADC B



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WITH HIGH-PRECISION CLAMP

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Terminal Functions (Continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
QC DGND	44	I	Digital ground for output of ADC C
QC DV _{DD}	35	I	Digital V _{DD} for output of ADC C
RB A	1	I	Reference voltage bottom of ADC A
RB B	48	I	Reference voltage bottom of ADC B
RB C	33	I	Reference voltage bottom of ADC C
RT A	61	I	Reference voltage top of ADC A. The nominal externally applied DC voltage between the RT A terminal and the RB A terminal is 2 V for video signals.
RT B	52	I	Reference voltage top of ADC B. The nominal externally applied DC voltage between the RT B terminal and the RB B terminal is 2 V for video signals.
RT C	29	I	Reference voltage top of ADC C. The nominal externally applied DC voltage between the RT C terminal and the RB C terminal is 2 V for video signals.
TEST	4	I	Test. This terminal should be tied low when using this device.

absolute maximum ratings†

Supply voltage, V _{CC} , V _{DD}	7 V
Reference voltage input range, V _{ref} (RT A), V _{ref} (RT B), V _{ref} (RT C), V _{ref} (RB A), V _{ref} (RB B), V _{ref} (RB C)	AGND to V _{CC}
Analog input voltage range	AGND to V _{CC}
Digital input voltage range, V _I	DGND to V _{DD}
Digital output voltage range, V _O	DGND to V _{DD}
Operating free-air temperature range, T _A	-20°C to 75°C
Storage temperature range, T _{stg}	-55°C to 150°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT	
Supply voltage	V _{CC} -AGND	4.75	5	5.25	V
	V _{DD} -DGND	4.75	5	5.25	
	AGND-DGND	-100	0	100	mV
Reference input voltage, V _{ref} (RT A), V _{ref} (RT B), V _{ref} (RT C)	V _{ref} (RB)+2		V _{CC}	V	
Reference input voltage, V _{ref} (RB A), V _{ref} (RB B), V _{ref} (RB C)	0		V _{ref} (RT)-2	V	
Analog input voltage, V _I	0		V _{ref} (RT)	V	
High-level input voltage, V _{IH}	4			V	
Low-level input voltage, V _{IL}			1	V	
High-level pulse duration, t _w (H)	25			ns	
Low-level pulse duration, t _w (L)	25			ns	
Setup time for INIT input, t _{su1}	5			ns	
Operating free-air temperature range, T _A	-20		75	°C	



TLC5733
20 MSPS 3-CHANNEL ANALOG-TO-DIGITAL CONVERTER
WITH HIGH-PRECISION CLAMP

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electrical characteristics at $V_{DD} = 5\text{ V}$, $V_{ref(RT)} = 2.5\text{ V}$, $V_{ref(BB)} = 0.5\text{ V}$, $f_s = 20\text{ MSPS}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Clamp level accuracy			±1		LSB
R_{ref} Reference voltage resistor	Measured between RT and RB	160	220	350	Ω
C_i Analog input capacitance	$V_I = 1.5\text{ V} + 0.07\text{ V}_{rms}$		16		pF
I_{IH} High-level input current	$V_{DD} = \text{MAX}^\dagger$, $V_{IH} = V_{DD}$			5	μA
I_{IL} Low-level input current	$V_{DD} = \text{MAX}^\dagger$, $V_{IL} = 0$			5	μA
I_{OH} High-level output current	$V_{DD} = \text{MIN}^\dagger$, $V_{OH} = V_{DD} - 0.5\text{ V}$	-1.5			mA
I_{OL} Low-level output current	$V_{DD} = \text{MIN}^\dagger$, $V_{OL} = 0.4\text{ V}$	2.5			mA
I_{OZH} High-level output leakage current	$V_{DD} = \text{MAX}^\dagger$, $V_{OH} = V_{DD}$			16	μA
I_{OZL} Low-level output leakage current	$V_{DD} = \text{MIN}^\dagger$, $V_{OL} = 0$			16	μA
I_{CC} Supply current	$f_s = 20\text{ MSPS}$, NTSC ramp wave input			75	mA

† Conditions marked MIN or MAX are as stated in recommended operating conditions.

operating characteristics at $V_{DD} = 5\text{ V}$, $V_{ref(RT)} = 2.5\text{ V}$, $V_{ref(RB)} = 0.5\text{ V}$, $f_s = 20\text{ MSPS}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
E_{ZS} Zero-scale error	$V_{ref} = REFT - REFB = 2\text{ V}$	-18	-43	-68	mV
E_{FS} Full-scale error	$V_{ref} = REFT - REFB = 2\text{ V}$	-20	0	20	mV
E_L Linearity error	$f_s = 20\text{ MSPS}$, $V_I = 0.5\text{ V to } 2.5\text{ V}$		±0.4	±0.75	LSB
	$f_s = 20\text{ MSPS}$, $T_A = -20^\circ\text{C to } 75^\circ\text{C}$, $V_I = 0.5\text{ V to } 2.5\text{ V}$		±0.4	±1	
E_D Linearity error, differential	$f_s = 20\text{ MSPS}$, $V_I = 0.5\text{ V to } 2.5\text{ V}$		±0.3	±0.5	LSB
	$f_s = 20\text{ MSPS}$, $T_A = -20^\circ\text{C to } 75^\circ\text{C}$, $V_I = 0.5\text{ V to } 2.5\text{ V}$		±0.3	±0.75	
f_s Maximum conversion rate	$V_I = 0.5\text{ V} - 2.5\text{ V}$, $f_I = 1\text{-kHz ramp wave form}$	20			MSPS
BW Analog input bandwidth	At -1 dB		14		MHz
t_{pd} Digital output delay time	$C_L = 10\text{ pF}$		18	30	ns
Differential gain	NTSC 40 IRE modulation wave, $f_s = 14.3\text{ MSPS}$		1%		
Differential phase			0.7		deg
t_{AJ} Aperture jitter time			30		ps
t_{ps} Sampling delay time			4		ns

TLC5733 20 MSPS 3-CHANNEL ANALOG-TO-DIGITAL CONVERTER WITH HIGH-PRECISION CLAMP

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detailed description

clamp function

The clamp function is optimized for a YUV video signal and has two clamp modes. The first mode uses the COMPOSITE SYNC signal as the input to the EXTCLP terminal to generate an internal clamp pulse and the second mode uses an externally generated clamp pulse as the input to the EXTCLP terminal.

In the first mode, the device detects false pulses in the COMPOSITE SYNC signal by monitoring the rising edges and falling edges of the COMPOSITE SYNC signal pulses. This monitoring prevents faulty operation caused by disturbances and missing pulses of the COMPOSITE SYNC signal input on EXTCLP and external spike noise. When fault pulses are detected, the device internally generates a train of clamp pulses at the proper positions (1H) by an internal 910-counter for NTSC and a 1136-counter for PAL. The device checks clamp pulses for 1H time and generates clamp pulses at correct positions if COMPOSITE SYNC pulses are in error in time.

The internal counter continually produces a horizontal sync period (1H) that is NTSC or PAL compatible as selected by the condition of the NT/PAL terminal.

clamp voltages and selection

Table 1 shows the clamping level during the clamp interval. Table 2 shows the selection of the internal or external clamp pulse. With either NTSC or PAL, the internal clamp pulse is always used.

Table 1. Clamp Level (Internal Connection Level)

CHANNEL OF ADC	OUTPUT CODE	APPLICATION
ADC A - $V_I(A)$	00010000	Y
ADC B - $V_I(B)$	10000000	(U, V)
ADC C - $V_I(C)$	10000000	(U, V)

Table 2. Clamp Level (Internal Connection Level)

CONDITION			FUNCTION (EACH ADC)	
CLPEN	EXTCLP	NT/PAL	INTERNAL CLAMP	CLAMP PULSE
L	⌋	Don't Care	Inactive	External clamp pulse
	L	Don't Care	Inactive	No clamping
H	COMPOSITE SYNC input	L	Active	Synchronous with NTSC
		H	Active	Synchronous with PAL

The clamp circuit is shown in Figure 6. The clamp voltage is stored on capacitor C2 during the back porch of the horizontal blanking period.

During the clamp pulse the input to channel A is clamped to

$$V_C(A) = (16/256) \times (\text{voltage difference from terminal RT A to RB A})$$

$$V_C(B) = (128/256) \times (\text{voltage difference from terminal RT B to RB B})$$

$$V_C(C) = (128/256) \times (\text{voltage difference from terminal RT C to RB C})$$

COMPOSITE SYNC time monitoring

- When CLPEN is high, COMPOSITE SYNC generates an internal clamp pulse on the horizontal blanking interval back porch. The TLC5733 has a timing window into which the horizontal sync tip must occur. There is a noise time window for the falling edge and a noise time window for the rising edge. Refer to Figure 1, Figure 2, and Table 3.

correct COMPOSITE SYNC timing

The Noise Gate 1 signal provides the timing window for the COMPOSITE SYNC falling edge. After an interval A of 867 clocks for NTSC or 1075 for PAL from the last falling edge of COMPOSITE SYNC, Noise Gate 1 goes high for 43 clocks for NTSC or 61 clocks for PAL (interval B). The falling edge of the input signal to the EXTCLP terminal can occur at any time within this window to be a valid COMPOSITE SYNC falling edge.

The Noise Gate 2 signal provides the timing window for the COMPOSITE SYNC rising edge. On the falling edge of the horizontal sync tip, the internal logic generates Noise Gate 2 as a low signal for 58 clocks (interval C) for both NTSC and PAL and then returns to a high active state. If, at this time, the input to the EXTCLP terminal is still low, it is considered a valid COMPOSITE SYNC signal.

normal clamp pulse generation

On the rising edge of the COMPOSITE SYNC signal, the internal logic generates an internal delay (interval D) and then generates the internal positive clamp pulse 54 clocks wide (interval F).

clamp operation with incorrect COMPOSITE SYNC timing

noise suppression

If the input to the EXTCLP terminal goes low prior to Noise Gate 1 going high (within 43 clocks for NTSC or 61 clocks for PAL of the normal 1H timing for the falling edge of COMPOSITE SYNC) then that input is not considered a valid COMPOSITE SYNC and is ignored.

If the input to the EXTCLP terminal is high when Noise Gate 2 goes to the high state, the input signal is considered noise and is ignored.

Therefore, the correct signal must be high a maximum of 43 clocks for NTSC or 61 clocks for PAL, before the 1H timing, to be a valid sync signal. Also, the input to the EXTCLP terminal must be at least 58 clocks wide (interval C) to be valid.

This function of monitoring the timing eliminates spurious noise spikes from falsely synchronizing the system.

timing error of COMPOSITE SYNC

The internal counter resets to zero on the first falling edge of COMPOSITE SYNC. After that time, if there is a missing COMPOSITE SYNC signal, then the internal logic waits an interval of 76 clocks (interval E) for NTSC or 93 for PAL from the counter zero count and then generates an internal clamp pulse 54 clocks wide (interval F).

This function maintains the synchronization pattern when COMPOSITE SYNC is not present.

summary of device operation with COMPOSITE SYNC

This internal timing allows the TLC5733 to correctly position the clamp pulse when an external COMPOSITE SYNC input occurs as follows:

- Is delayed with respect to the horizontal sync period
- Is early with respect to the horizontal sync period
- Is nonexistent during the horizontal sync period
- Has falling edge noise spikes within the horizontal sync period

The device operation is summarized as follows for these improper external clamp conditions.

- Under all four conditions on the EXTCLP terminal, the internal clamp generation circuit generates a clamp pulse at the proper time after the horizontal sync period as shown in Figure 1.
- The TLC5733 internal clamp circuit generates an internal clamp pulse each 1H time for the entire time interval that the COMPOSITE SYNC input is missing.

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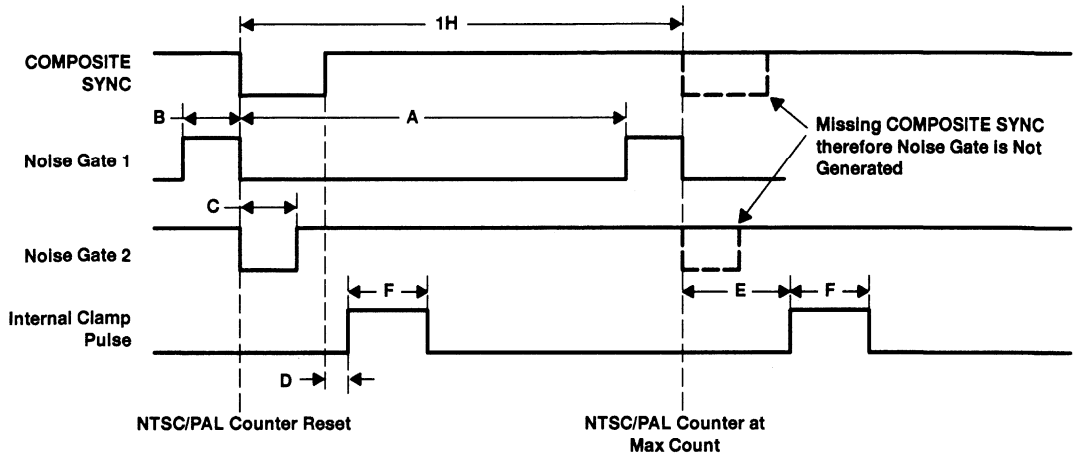


Figure 1. COMPOSITE SYNC and Internal Clamp Timing

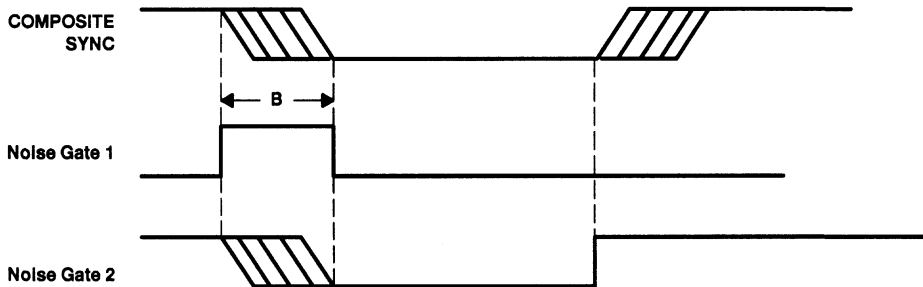


Figure 2. Proper COMPOSITE SYNC Timing

Table 3. Sync and Clamp Timing for NTSC and PAL with CLK = 4 fsc

TIME INTERVAL	NTSC		PAL	
	NO. OF CLOCKS	TIME (μs)	NO. OF CLOCKS	TIME (μs)
A	867	60.6	1075	60.7
B	43	3	61	3.5
C	58	4.05	58	3.27
D	6	0.42	6	0.34
E	76	5.3	93	5.25
F	54	3.77	84	4.74
fsc	3.58 MHz		4.43 MHz	

using an external clamp pulse

When CLPEN is taken low, the EXTCLP terminal accepts an externally generated active-high clamp pulse. This pulse must occur within the horizontal blanking interval back porch. CLPEN low inhibits the internal counters and no internal clamp pulse is generated.



output digital code (for each channel of ADC)

Table 4. Input Signal Versus Output Digital Code

INPUT SIGNAL VOLTAGE	STEP	DIGITAL OUTPUT CODE							
		MSB							LSB
$V_{ref(RT)}$	255	1	1	1	1	1	1	1	1
•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•
•	128	1	0	0	0	0	0	0	0
•	127	0	1	1	1	1	1	1	1
•	•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•	•
$V_{ref(RB)}$	0	0	0	0	0	0	0	0	0

output data format

The TLC5733 can select three output data formats to various TV/VCR (video) data processing by the combination of MODE0 and MODE1. The output is synchronous when INIT is taken high.

Table 5. Output Data Format Selection

CONDITION		OUTPUT DATA	
MODE1	MODE0	OUTPUT DATA FORMAT	RATIO OF Y:U:V
L	L	Format 1	4:1:1
L	H	Format 2	4:4:4
H	L	Format 3	4:2:2
H	H	Not used	N/A

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output data format (continued)

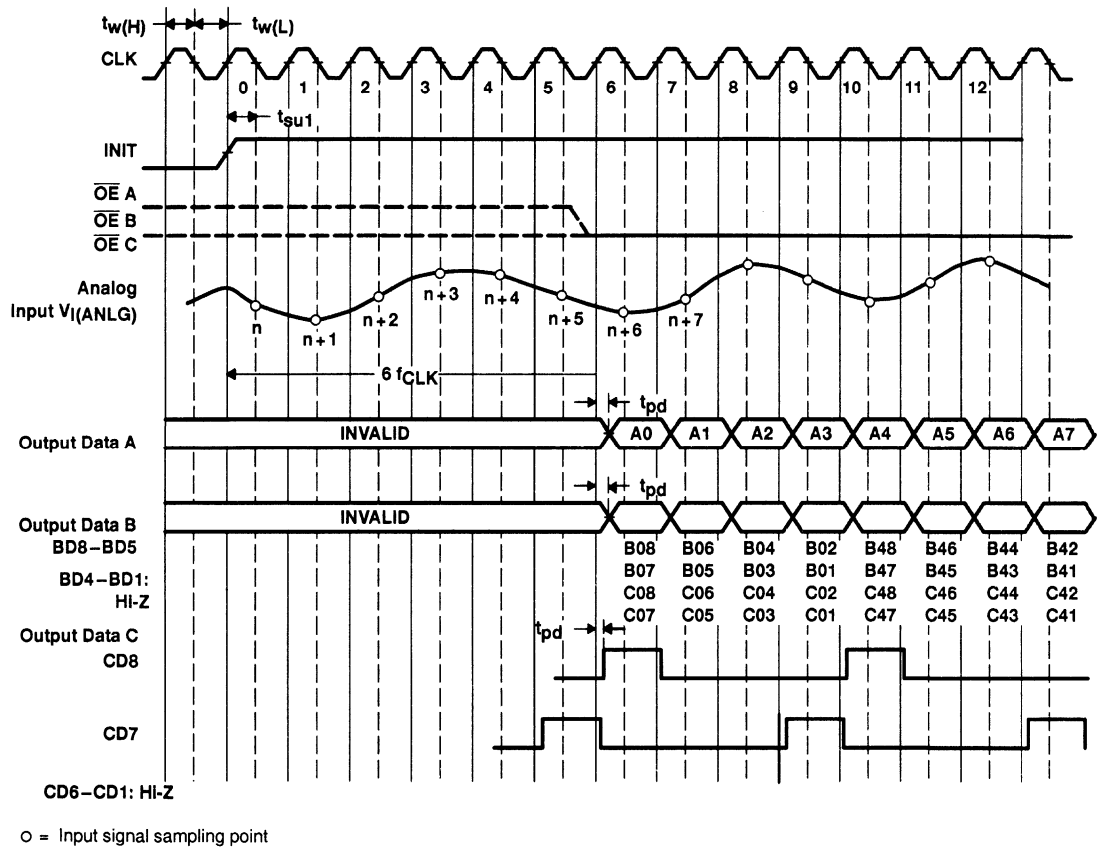


Figure 3. Format 1, 4:1:1

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output data format (continued)

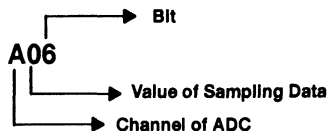


Table 6. Format 1

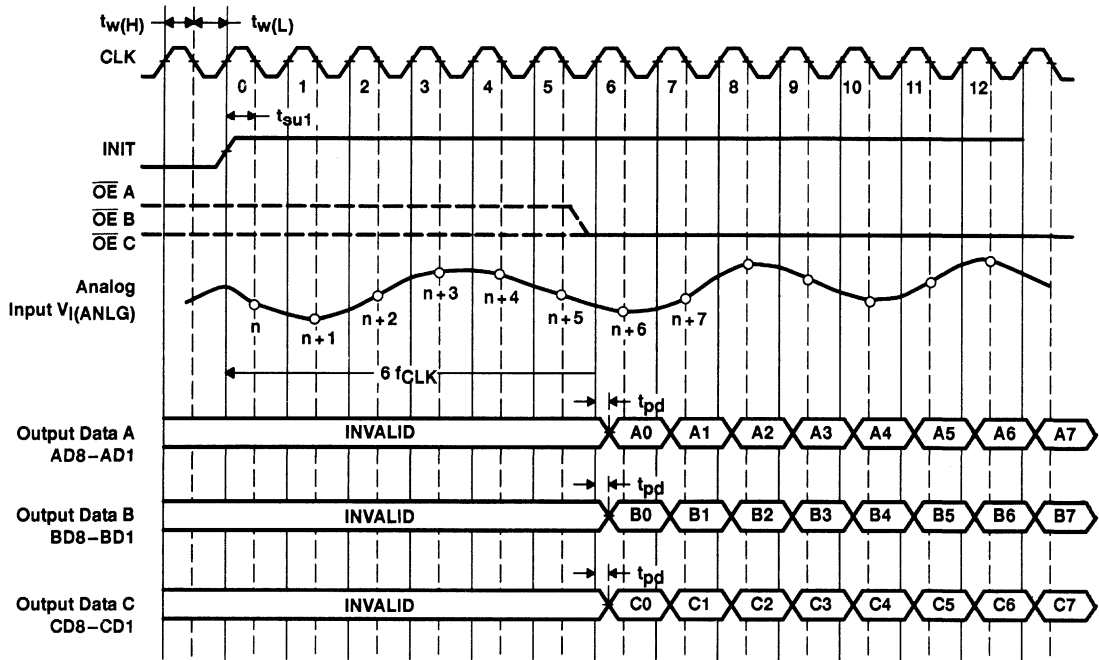
CHANNEL OF ADC	BIT	OUTPUT DATA							
A	AD8	A08	A18	A28	A38	A48	A58	A68	A78
	AD7	A07	A17	A27	A37	A47	A57	A67	A77
	AD6	A06	A16	A26	A36	A46	A56	A66	A76
	AD5	A05	A15	A25	A35	A45	A55	A65	A75
	AD4	A04	A14	A24	A34	A44	A54	A64	A74
	AD3	A03	A13	A23	A33	A43	A53	A63	A73
	AD2	A02	A12	A22	A32	A42	A52	A62	A72
	AD1	A01	A11	A21	A31	A41	A51	A61	A71
B	BD8	B08	B06	B04	B02	B48	B46	B44	B42
	BD7	B07	B05	B03	B01	B47	B45	B43	B41
	BD6	C08	C06	C04	C02	C48	C46	C44	C42
	BD5	C07	C05	C03	C01	C47	C45	C43	C41
	BD4	Hi-Z							→
	BD3	Hi-Z							→
	BD2	Hi-Z							→
	BD1	Hi-Z							→
C	CD8	H	L	L	L	H	L	L	L
	CD7	L	L	L	H	L	L	L	H
	CD6	Hi-Z							→
	CD5	Hi-Z							→
	CD4	Hi-Z							→
	CD3	Hi-Z							→
	CD2	Hi-Z							→
	CD1	Hi-Z							→
CLK (see Note 2)		6	7	8	9	10	11	12	13

NOTES: 1. Hi-Z = high impedance
 2. The value of the first sampling clock at A–D conversion is CLK 0.

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output data format (continued)



○ = Input signal sampling point

Figure 4. Format 2, 4:4:4

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output data format (continued)

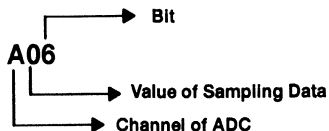


Table 7. Format 2

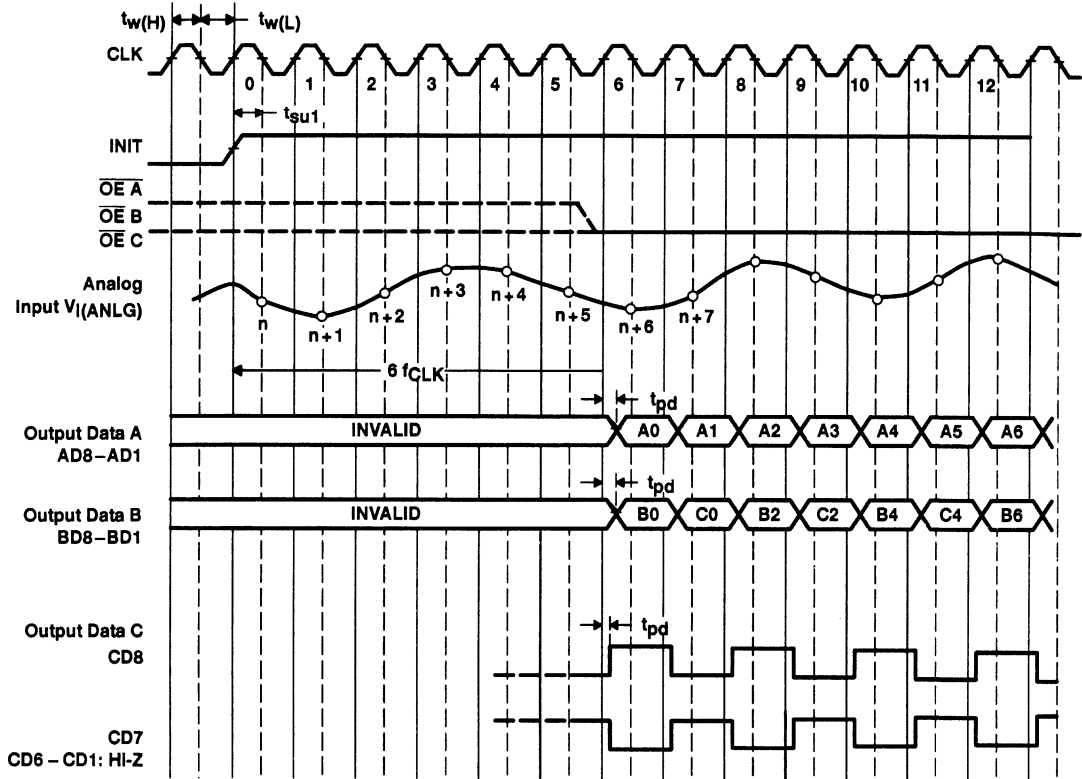
CHANNEL OF ADC	BIT	OUTPUT DATA							
A	AD8	A08	A18	A28	A38	A48	A58	A68	A78
	AD7	A07	A17	A27	A37	A47	A57	A67	A77
	AD6	A06	A16	A26	A36	A46	A56	A66	A76
	AD5	A05	A15	A25	A35	A45	A55	A65	A75
	AD4	A04	A14	A24	A34	A44	A54	A64	A74
	AD3	A03	A13	A23	A33	A43	A53	A63	A73
	AD2	A02	A12	A22	A32	A42	A52	A62	A72
	AD1	A01	A11	A21	A31	A41	A51	A61	A71
B	BD8	B08	B18	B28	B38	B48	B58	B68	B78
	BD7	B07	B17	B27	B37	B47	B57	B67	B77
	BD6	B06	B16	B26	B36	B46	B56	B66	B76
	BD5	B05	B15	B25	B35	B45	B55	B65	B75
	BD4	B04	B14	B24	B34	B44	B54	B64	B74
	BD3	B03	B13	B23	B33	B43	B53	B63	B73
	BD2	B02	B12	B22	B32	B42	B52	B62	B72
	BD1	B01	B11	B21	B31	B41	B51	B61	B71
C	CD8	C08	C18	C28	C38	C48	C58	C68	C78
	CD7	C07	C17	C27	C37	C47	C57	C67	C77
	CD6	C06	C16	C26	C36	C46	C56	C66	C76
	CD5	C05	C15	C25	C35	C45	C55	C65	C75
	CD4	C04	C14	C24	C34	C44	C54	C64	C74
	CD3	C03	C13	C23	C33	C43	C53	C63	C73
	CD2	C02	C12	C22	C32	C42	C52	C62	C72
	CD1	C01	C11	C21	C31	C41	C51	C61	C71
CLK (see Note 2)		6	7	8	9	10	11	12	13

NOTE 2: The value of the first sampling clock at A–D conversion is CLK 0.

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output data format (continued)



○ - Input signal sampling point

Figure 5. Format 3, 4:2:2

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output data format (continued)

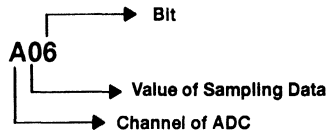


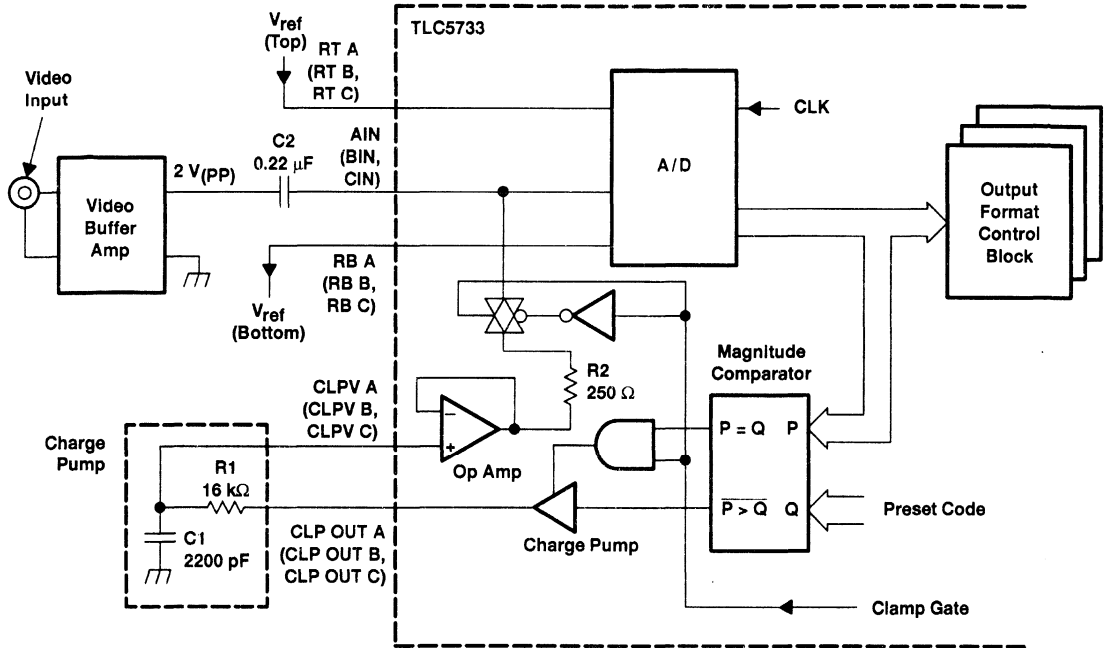
Table 8. Format 3

CHANNEL OF ADC	BIT	OUTPUT DATA							
A	AD8	A08	A18	A28	A38	A48	A58	A68	A78
	AD7	A07	A17	A27	A37	A47	A57	A67	A77
	AD6	A06	A16	A26	A36	A46	A56	A66	A76
	AD5	A05	A15	A25	A35	A45	A55	A65	A75
	AD4	A04	A14	A24	A34	A44	A54	A64	A74
	AD3	A03	A13	A23	A33	A43	A53	A63	A73
	AD2	A02	A12	A22	A32	A42	A52	A62	A72
	AD1	A01	A11	A21	A31	A41	A51	A61	A71
	B	BD8	B08	C08	B28	C28	B48	C48	B68
BD7		B07	C07	B27	C27	B47	C47	B67	C67
BD6		B06	C06	B26	C26	B46	C46	B66	C66
BD5		B05	C05	B25	C25	B45	C45	B65	C65
BD4		B04	C04	B24	C24	B44	C44	B64	C64
BD3		B03	C03	B23	C23	B43	C43	B63	C63
BD2		B02	C02	B22	C22	B42	C42	B62	C62
BD1		B01	C01	B21	C21	B41	C41	B61	C61
C		CD8	H	L	H	L	H	L	H
	CD7	L	H	L	H	L	H	L	H
	CD6	Hi-Z							→
	CD5	Hi-Z							→
	CD4	Hi-Z							→
	CD3	Hi-Z							→
	CD2	Hi-Z							→
CD1	Hi-Z							→	
CLK (see Note 2)		6	7	8	9	10	11	12	13

- NOTES: 1. Hi-Z = high impedance
 2. The value of the first sampling clock at A–D conversion is CLK 0.

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WITH HIGH-PRECISION CLAMP
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APPLICATION INFORMATION



FUNCTION FOR FEEDBACK CLAMP AND CHARGE PUMP

INPUT DATA CONDITIONS	OUTPUT		CHARGE PUMP CONDITIONS
	$\overline{P} = \overline{Q}$	$\overline{P} > \overline{Q}$	
$P < Q$	Active	H	Charge
$P = Q$	Hold	Z	Hold
$P > Q$	Active	L	Discharge

Figure 6. Feedback Clamp Circuit

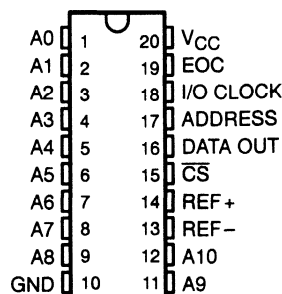
TLV1543C, TLV1543M

3.3-V 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

SLAS072C – DECEMBER 1992 – REVISED MARCH 1995

- 3.3-V Supply Operation
- 10-Bit-Resolution A/D Converter
- 11 Analog Input Channels
- Three Built-In Self-Test Modes
- Inherent Sample and Hold
- Total Unadjusted Error . . . ± 1 LSB Max
- On-Chip System Clock
- End-of-Conversion (EOC) Output
- Pin Compatible With TLC1543
- CMOS Technology

DB, DW, FK, J, OR N PACKAGE
(TOP VIEW)



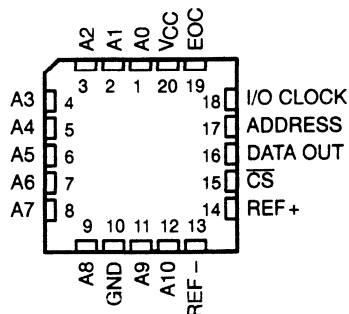
description

The TLV1543C and TLV1543M are CMOS 10-bit, switched-capacitor, successive-approximation, analog-to-digital converters. These devices have three inputs and a 3-state output [chip select (\overline{CS}), input-output clock (I/O CLOCK), address input (ADDRESS), and data output (DATA OUT)] that provide a direct 4-wire interface to the serial port of a host processor. The devices allow high-speed data transfers from the host.

In addition to a high-speed A/D converter and versatile control capability, these devices have an on-chip 14-channel multiplexer that can select any one of 11 analog inputs or any one of three internal self-test voltages. The sample-and-hold function is automatic. At the end of A/D conversion, the end-of-conversion (EOC) output goes high to indicate that conversion is complete. The converter incorporated in the devices features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating free-air temperature range.

The TLV1543C is characterized for operation from 0°C to 70°C. The TLV1543M is characterized for operation over the full military temperature range of -55°C to 125°C.

FN PACKAGE
(TOP VIEW)



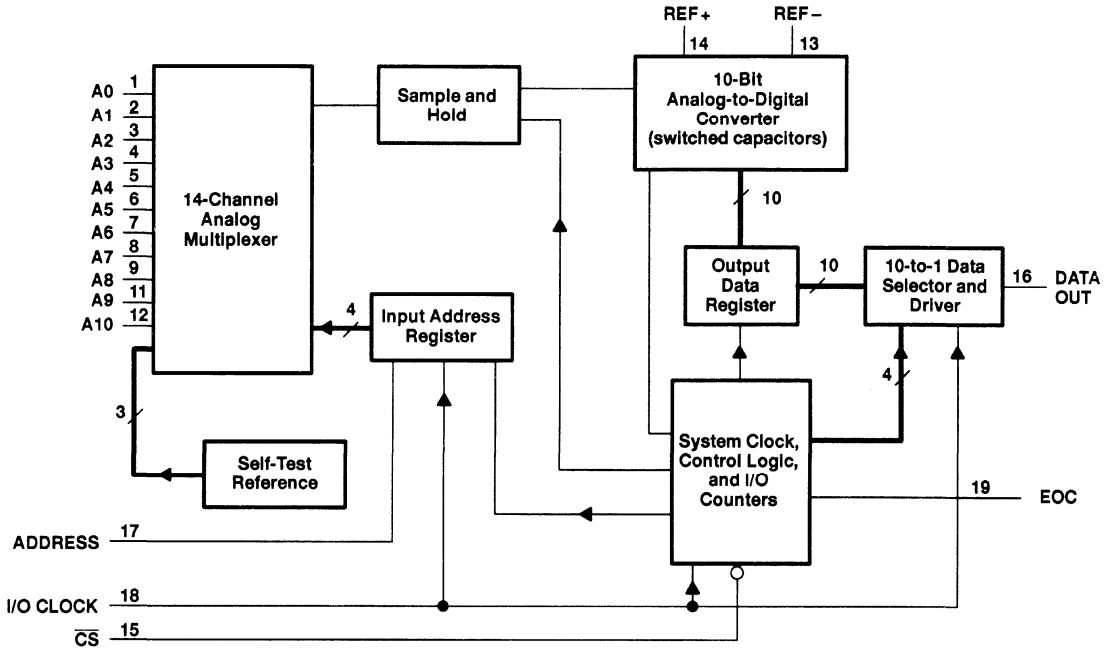
AVAILABLE OPTIONS

T _A	PACKAGE					
	SMALL OUTLINE (DB)	SMALL OUTLINE (DW)	CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)	PLASTIC CHIP CARRIER (FN)
0°C to 70°C	TLV1543CDB	TLV1543CDW	—	—	TLV1543CN	TLV1543CFN
-55°C to 125°C	—	—	TLV1543MFK	TLV1543MJ	—	—

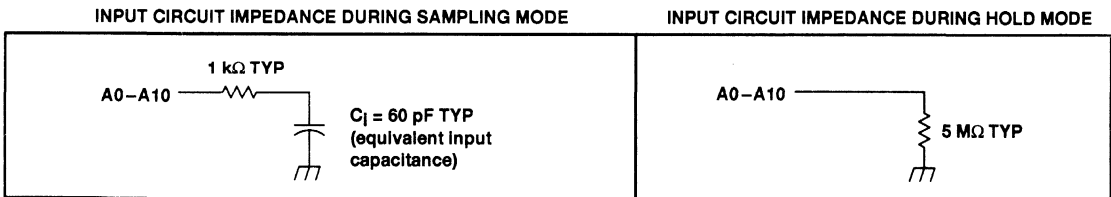
TLV1543C, TLV1543M
3.3-V 10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 ANALOG INPUTS

SLAS072C - DECEMBER 1992 - REVISED MARCH 1995

functional block diagram



typical equivalent inputs



TLV1543C, TLV1543M
3.3-V 10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ADDRESS	17	I	Serial address. A 4-bit serial address selects the desired analog input or test voltage that is to be converted next. The address data is presented with the MSB first and is shifted in on the first four rising edges of I/O CLOCK. After the four address bits have been read into the address register, ADDRESS is ignored for the remainder of the current conversion period.
A0–A10	1–9, 11, 12	I	Analog signal. The 11 analog inputs are applied to A0–A10 and are internally multiplexed. The driving source impedance should be less than or equal to 1 k Ω .
\overline{CS}	15	I	Chip select. A high-to-low transition on \overline{CS} resets the internal counters and controls and enables DATA OUT, ADDRESS, and I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock. A low-to-high transition disables ADDRESS and I/O CLOCK within a setup time plus two falling edges of the internal system clock.
DATA OUT	16	O	The 3-state serial output for the A/D conversion result. DATA OUT is in the high-impedance state when \overline{CS} is high and active when \overline{CS} is low. With a valid chip select, DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB value of the previous conversion result. The next falling edge of I/O CLOCK drives DATA OUT to the logic level corresponding to the next most significant bit, and the remaining bits are shifted out in order with the LSB appearing on the ninth falling edge of I/O CLOCK. On the tenth falling edge of I/O CLOCK, DATA OUT is driven to a low logic level so that serial interface data transfers of more than ten clocks produce zeroes as the unused LSBs.
EOC	19	O	End of conversion. EOC goes from a high- to a low- logic level on the trailing edge of the tenth I/O CLOCK and remains low until the conversion is complete and data are ready for transfer.
GND	10	I	The ground return terminal for the internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.
I/O CLOCK	18	I	Input/output clock. I/O CLOCK receives the serial I/O CLOCK input and performs the following four functions: 1) It clocks the four input address bits into the address register on the first four rising edges of I/O CLOCK with the multiplex address available after the fourth rising edge. 2) On the fourth falling edge of I/O CLOCK, the analog input voltage on the selected multiplex input begins charging the capacitor array and continues to do so until the tenth falling edge of I/O CLOCK. 3) It shifts the nine remaining bits of the previous conversion data out on DATA OUT. 4) It transfers control of the conversion to the internal state controller on the falling edge of the tenth clock.
REF +	14	I	The upper reference voltage value (nominally V_{CC}) is applied to REF +. The maximum input voltage range is determined by the difference between the voltage applied to REF + and the voltage applied to the REF – terminal.
REF –	13	I	The lower reference voltage value (nominally ground) is applied to REF –.
V_{CC}	20	I	Positive supply voltage

detailed description

With chip select (\overline{CS}) inactive (high), the ADDRESS and I/O CLOCK inputs are initially disabled and DATA OUT is in the high-impedance state. When the serial interface takes \overline{CS} active (low), the conversion sequence begins with the enabling of I/O CLOCK and ADDRESS and the removal of DATA OUT from the high-impedance state. The host then provides the 4-bit channel address to ADDRESS and the I/O CLOCK sequence to I/O CLOCK. During this transfer, the host serial interface also receives the previous conversion result from DATA OUT. I/O CLOCK receives an input sequence that is between 10 and 16 clocks long from the host. The first four I/O clocks load the address register with the 4-bit address on ADDRESS selecting the desired analog channel and the next six clocks providing the control timing for sampling the analog input.

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detailed description (continued)

There are six basic serial interface timing modes that can be used with the device. These modes are determined by the speed of I/O CLOCK and the operation of \overline{CS} as shown in Table 1. These modes are (1) a fast mode with a 10-clock transfer and \overline{CS} inactive (high) between conversion cycles, (2) a fast mode with a 10-clock transfer and \overline{CS} active (low) continuously, (3) a fast mode with an 11- to 16-clock transfer and \overline{CS} inactive (high) between conversion cycles, (4) a fast mode with a 16-bit transfer and \overline{CS} active (low) continuously, (5) a slow mode with an 11- to 16-clock transfer and \overline{CS} inactive (high) between conversion cycles, and (6) a slow mode with a 16-clock transfer and \overline{CS} active (low) continuously.

The MSB of the previous conversion appears on DATA OUT on the falling edge of \overline{CS} in mode 1, mode 3, and mode 5, on the rising edge of EOC in mode 2 and mode 4, and following the 16th clock falling edge in mode 6. The remaining nine bits are shifted out on the next nine falling edges of I/O CLOCK. Ten bits of data are transmitted to the host through DATA OUT. The number of serial clock pulses used also depends on the mode of operation, but a minimum of ten clock pulses is required for conversion to begin. On the 10th clock falling edge, the EOC output goes low and returns to the high logic level when conversion is complete and the result can be read by the host. On the 10th clock falling edge, the internal logic takes DATA OUT low to ensure that the remaining bit values are zero if the I/O CLOCK transfer is more than ten clocks long.

Table 1 lists the operational modes with respect to the state of \overline{CS} , the number of I/O serial transfer clocks that can be used, and the timing edge on which the MSB of the previous conversion appears at the output.

Table 1. Mode Operation

MODES		\overline{CS}	NO. OF I/O CLOCKS	MSB AT DATA OUT†	TIMING DIAGRAM
Fast Modes	Mode 1	High between conversion cycles	10	\overline{CS} falling edge	Figure 9
	Mode 2	Low continuously	10	EOC rising edge	Figure 10
	Mode 3	High between conversion cycles	11 to 16‡	\overline{CS} falling edge	Figure 11
	Mode 4	Low continuously	16‡	EOC rising edge	Figure 12
Slow Modes	Mode 5	High between conversion cycles	11 to 16‡	\overline{CS} falling edge	Figure 13
	Mode 6	Low continuously	16‡	16th clock falling edge	Figure 14

† These edges also initiate serial-interface communication.

‡ No more than 16 clocks should be used.

fast modes

The device is in a fast mode when the serial I/O CLOCK data transfer is completed before the conversion is completed. With a 10-clock serial transfer, the device can only run in a fast mode since a conversion does not begin until the falling edge of the 10th I/O CLOCK.

mode 1: fast mode, \overline{CS} inactive (high) between conversion cycles, 10-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer is ten clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables the I/O CLOCK and ADDRESS terminals within a setup time plus two falling edges of the internal system clock.

mode 2: fast mode, \overline{CS} active (low) continuously, 10-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer is ten clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions; the rising edge of EOC then begins each sequence by removing DATA OUT from the low logic level, allowing the MSB of the previous conversion to appear immediately on this output.



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mode 3: fast mode, \overline{CS} inactive (high) between conversion cycles, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables the I/O CLOCK and ADDRESS terminals within a setup time plus two falling edges of the internal system clock.

mode 4: fast mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions; the rising edge of EOC then begins each sequence by removing DATA OUT from the low logic level, allowing the MSB of the previous conversion to appear immediately on this output.

slow modes

In a slow mode, the conversion is completed before the serial I/O CLOCK data transfer is completed. A slow mode requires a minimum 11-clock transfer into I/O CLOCK, and the rising edge of the eleventh clock must occur before the conversion period is complete; otherwise, the device loses synchronization with the host serial interface, and \overline{CS} has to be toggled to initialize the system. The eleventh rising edge of the I/O CLOCK must occur within 9.5 μ s after the tenth I/O clock falling edge.

mode 5: slow mode, \overline{CS} inactive (high) between conversion cycles, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables the I/O CLOCK and ADDRESS terminals within a setup time plus two falling edges of the internal system clock.

mode 6: slow mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. The falling edge of the sixteenth I/O CLOCK then begins each sequence by removing DATA OUT from the low state, allowing the MSB of the previous conversion to appear immediately at DATA OUT. The device is then ready for the next 16-clock transfer initiated by the serial interface.

address bits

The 4-bit analog channel-select address for the next conversion cycle is presented to the ADDRESS terminal (MSB first) and is clocked into the address register on the first four leading edges of I/O CLOCK. This address selects one of 14 inputs (11 analog inputs or 3 internal test inputs).

analog inputs and test modes

The 11 analog inputs and the 3 internal test inputs are selected by the 14-channel multiplexer according to the input address as shown in Tables 2 and 3. The input multiplexer is a break-before-make type to reduce input-to-input noise injection resulting from channel switching.

Sampling of the analog input starts on the falling edge of the fourth I/O CLOCK, and sampling continues for six I/O CLOCK periods. The sample is held on the falling edge of the tenth I/O CLOCK. The three test inputs are applied to the multiplexer, sampled, and converted in the same manner as the external analog inputs.

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Table 2. Analog-Channel-Select Address

ANALOG INPUT SELECTED	VALUE SHIFTED INTO ADDRESS INPUT	
	BINARY	HEX
A0	0000	0
A1	0001	1
A2	0010	2
A3	0011	3
A4	0100	4
A5	0101	5
A6	0110	6
A7	0111	7
A8	1000	8
A9	1001	9
A10	1010	A

Table 3. Test-Mode-Select Address

INTERNAL SELF-TEST VOLTAGE SELECTED†	VALUE SHIFTED INTO ADDRESS INPUT		OUTPUT RESULT (HEX)‡
	BINARY	HEX	
$\frac{V_{ref+} - V_{ref-}}{2}$	1011	B	200
V_{ref-}	1100	C	000
V_{ref+}	1101	D	3FF

† V_{ref+} is the voltage applied to the REF + input, and V_{ref-} is the voltage applied to the REF – input.

‡ The output results shown are the ideal values and vary with the reference stability and with internal offsets.

converter and analog input

The CMOS threshold detector in the successive-approximation conversion system determines each bit by examining the charge on a series of binary-weighted capacitors (see Figure 1). In the first phase of the conversion process, the analog input is sampled by closing the S_C switch and all S_T switches simultaneously. This action charges all the capacitors to the input voltage.

In the next phase of the conversion process, all S_T and S_C switches are opened and the threshold detector begins identifying bits by identifying the charge (voltage) on each capacitor relative to the reference (REF–) voltage. In the switching sequence, ten capacitors are examined separately until all ten bits are identified and the charge-convert sequence is repeated. In the first step of the conversion phase, the threshold detector looks at the first capacitor (weight = 512). Node 512 of this capacitor is switched to the REF+ voltage, and the equivalent nodes of all the other capacitors on the ladder are switched to REF–. If the voltage at the summing node is greater than the trip point of the threshold detector (approximately one-half the V_{CC} voltage), a bit 0 is placed in the output register and the 512-weight capacitor is switched to REF–. If the voltage at the summing node is less than the trip point of the threshold detector, a bit 1 is placed in the register and the 512-weight capacitor remains connected to REF+ through the remainder of the successive-approximation process. The process is repeated for the 256-weight capacitor, the 128-weight capacitor, and so forth down the line until all bits are counted.

With each step of the successive-approximation process, the initial charge is redistributed among the capacitors. The conversion process relies on charge redistribution to count and weigh the bits from MSB to LSB.



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converter and analog input (continued)

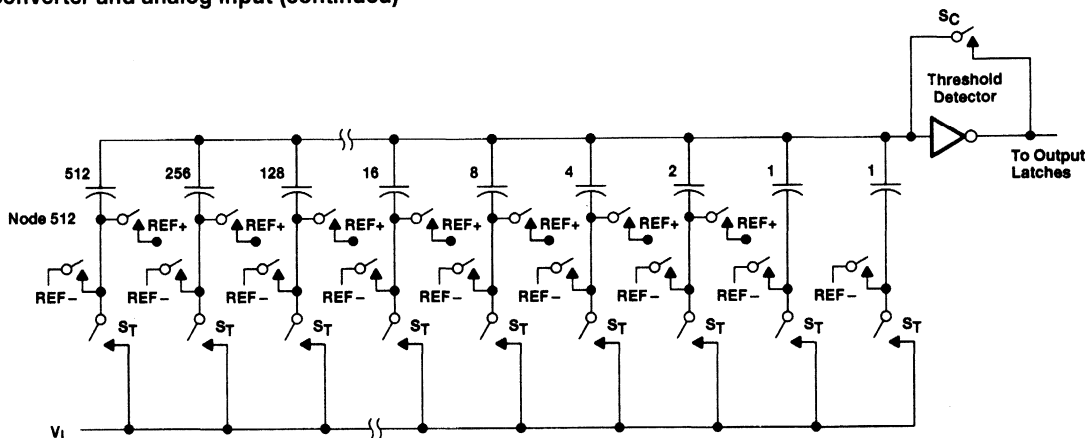


Figure 1. Simplified Model of the Successive-Approximation System

chip-select operation

The trailing edge of \overline{CS} starts all modes of operation, and \overline{CS} can abort a conversion sequence in any mode. A high-to-low transition on \overline{CS} within the specified time during an ongoing cycle aborts the cycle, and the device returns to the initial state (the contents of the output data register remain at the previous conversion result). Exercise care to prevent \overline{CS} from being taken low close to completion of conversion because the output data can be corrupted.

reference voltage inputs

There are two reference inputs used with these devices: REF+ and REF-. These voltage values establish the upper and lower limits of the analog input to produce a full-scale and zero-scale reading respectively. The values of REF+, REF-, and the analog input should not exceed the positive supply or be lower than GND consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF+ and at zero when the input signal is equal to or lower than REF-.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1):	TLV1543C	-0.5 V to 6.5 V
	TLV1543M	-0.5 V to 6 V
Input voltage range, V_I (any input)		-0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O		-0.3 V to $V_{CC} + 0.3$ V
Positive reference voltage, V_{ref+}		$V_{CC} + 0.1$ V
Negative reference voltage, V_{ref-}		-0.1 V
Peak input current (any input)		± 20 mA
Peak total input current (all inputs)		± 30 mA
Operating free-air temperature range, T_A :	TLV1543C	0°C to 70°C
	TLV1543M	-55°C to 125°C
Storage temperature range, T_{stg}		-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds		260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to digital ground with REF- and GND wired together (unless otherwise noted).

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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	TLV1543C	3	3.3	5.5	V
	TLV1543M	3	3.3	3.6	V
Positive reference voltage, V_{ref+} (see Note 2)		V_{CC}			V
Negative reference voltage, V_{ref-} (see Note 2)		0			V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)		2.5	V_{CC}	$V_{CC} + 0.2$	V
Analog input voltage (see Note 2)		0			V_{CC}
High-level control input voltage, V_{IH}	TLV1543C	$V_{CC} = 3\text{ V to }5.5\text{ V}$		2	V
	TLV1543M	$V_{CC} = 3\text{ V to }3.6\text{ V}$		2	V
Low-level control input voltage, V_{IL}	TLV1543C	$V_{CC} = 3\text{ V to }5.5\text{ V}$		0.6	V
	TLV1543M	$V_{CC} = 3\text{ V to }3.6\text{ V}$		0.8	V
Setup time, address bits at data input before I/O CLOCK \uparrow , $t_{su(A)}$ (see Figure 4)		100			ns
Hold time, address bits after I/O CLOCK \uparrow , $t_h(A)$ (see Figure 4)		0			ns
Hold time, \overline{CS} low after last I/O CLOCK \downarrow , $t_h(\overline{CS})$		0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su}(\overline{CS})$ (see Note 3)		1.425			μs
Clock frequency at I/O CLOCK (see Note 4)	TLC1543C	0		1.1	MHz
	TLC1543M	0		2.1	
Pulse duration, I/O CLOCK high, $t_{wH(I/O)}$		190			ns
Pulse duration, I/O CLOCK low, $t_{wL(I/O)}$		190			ns
Transition time, I/O CLOCK, $t_f(I/O)$ (see Note 5)		1			μs
Transition time, ADDRESS and \overline{CS} , $t_f(\overline{CS})$		10			μs
Operating free-air temperature, T_A	TLV1543C	0		70	$^{\circ}\text{C}$
	TLV1543M	-55		125	

- NOTES:
- Analog input voltages greater than that applied to REF+ convert as all ones (1111111111), while input voltages less than that applied to REF- convert as all zeros (0000000000). The device is functional with reference voltages down to 1 V ($V_{ref+} - V_{ref-}$); however, the electrical specifications are no longer applicable.
 - To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to control input signals. No attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.
 - For 11- to 16-bit transfers, after the tenth I/O CLOCK falling edge ($\leq 2\text{ V}$), at least one I/O clock rising edge ($\geq 2\text{ V}$) must occur within 9.5 μs .
 - This is the time required for the clock input signal to fall from V_{IHmin} to V_{ILmax} or to rise from V_{ILmax} to V_{IHmin} . In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 1 μs for remote data-acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 3\text{ V to }5.5\text{ V}$, I/O CLOCK frequency = 1.1 MHz for the TLV1543C,
 $V_{CC} = V_{ref+} = 3\text{ V to }3.6\text{ V}$, I/O CLOCK frequency = 2.1 MHz for the TLV1543M (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT	
V_{OH}	High-level output voltage	TLV1543C	$V_{CC} = 3\text{ V}$, $I_{OH} = -1.6\text{ mA}$	2.4			V	
			$V_{CC} = 3\text{ V to }5.5\text{ V}$, $I_{OH} = 20\text{ }\mu\text{A}$	$V_{CC}-0.1$			V	
	TLV1543M	$V_{CC} = 3\text{ V}$, $I_{OH} = -1.6\text{ mA}$	2.4			V		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$, $I_{OH} = 20\text{ }\mu\text{A}$	$V_{CC}-0.1$			V		
V_{OL}	Low-level output voltage	TLV1543C	$V_{CC} = 3\text{ V}$, $I_{OL} = 1.6\text{ mA}$			0.4	V	
			$V_{CC} = 3\text{ V to }5.5\text{ V}$, $I_{OL} = 20\text{ }\mu\text{A}$			0.1	V	
	TLV1543M	$V_{CC} = 3\text{ V}$, $I_{OL} = 1.6\text{ mA}$			0.4	V		
		$V_{CC} = 3\text{ V to }3.6\text{ V}$, $I_{OL} = 20\text{ }\mu\text{A}$			0.1	V		
I_{OZ}	Off-state (high-impedance-state) output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}				10	μA	
		$V_O = 0$, \overline{CS} at V_{CC}				-10		
I_{IH}	High-level input current	$V_I = V_{CC}$			0.005	2.5	μA	
I_{IL}	Low-level input current	$V_I = 0$			-0.005	-2.5	μA	
I_{CC}	Operating supply current	\overline{CS} at 0 V			0.8	2.5	mA	
Selected channel leakage current		Selected channel at V_{CC} , Unselected channel at 0 V				1	μA	
		Selected channel at 0 V, Unselected channel at V_{CC}				-1		
Maximum static analog reference current into REF +		$V_{ref+} = V_{CC}$, $V_{ref-} = \text{GND}$				10	μA	
C_i	Input capacitance, Analog inputs	TLV1543C			7	55	pF	
		TLV1543M			7			
	Input capacitance, Control inputs	TLV1543C				5	15	pF
		TLV1543M				5		

† All typical values are at $V_{CC} = 5\text{ V}$, $T_A = 25^\circ\text{C}$.

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operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 3\text{ V to }5.5\text{ V}$, I/O CLOCK frequency = 1.1 MHz for the TLV1543C,
 $V_{CC} = V_{ref+} = 3\text{ V to }3.6\text{ V}$, I/O CLOCK frequency = 2.1 MHz for the TLV1543M

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
	Linearity error (see Note 6)				±1	LSB
	Zero error (see Note 7)	See Note 2			±1	LSB
	Full-scale error (see Note 7)	See Note 2			±1	LSB
	Total unadjusted error (see Note 8)				±1	LSB
	Self-test output code (see Table 3 and Note 9)	ADDRESS = 1011		512		
		ADDRESS = 1100		0		
		ADDRESS = 1101		1023		
t_{conv}	Conversion time	See Figures 9–14			21	µs
t_c	Total cycle time (access, sample, and conversion)	See Figures 9–14 and Note 10			21 +10 I/O CLOCK periods	µs
t_{acq}	Channel acquisition time (sample)	See Figures 9–14 and Note 10			6	I/O CLOCK periods
t_v	Valid time, DATA OUT remains valid after I/O CLOCK↓	See Figure 6	10			ns
$t_d(I/O-DATA)$	Delay time, I/O CLOCK↓ to DATA OUT valid	See Figure 6			240	ns
$t_d(I/O-EOC)$	Delay time, tenth I/O CLOCK↓ to EOC↓	See Figure 7		70	240	ns
$t_d(EOC-DATA)$	Delay time, EOC↑ to DATA OUT (MSB)	See Figure 8			100	ns
t_{PZH}, t_{PZL}	Enable time, \overline{CS} ↓ to DATA OUT (MSB driven)	See Figure 3			1.3	µs
t_{PHZ}, t_{PLZ}	Disable time, \overline{CS} ↑ to DATA OUT (high impedance)	See Figure 3			150	ns
$t_r(EOC)$	Rise time, EOC	See Figure 8			300	ns
$t_f(EOC)$	Fall time, EOC	See Figure 7			300	ns
$t_r(\text{bus})$	Rise time, data bus	See Figure 6			300	ns
$t_f(\text{bus})$	Fall time, data bus	See Figure 6			300	ns
$t_d(I/O-CS)$	Delay time, tenth I/O CLOCK↓ to \overline{CS} ↓ to abort conversion (see Note 11)				9	µs

† All typical values are at $T_A = 25^\circ\text{C}$.

- NOTES: 2. Analog input voltages greater than that applied to REF + convert as all ones (1111111111), while input voltages less than that applied to REF – convert as all zeros (0000000000). The device is functional with reference voltages down to 1 V ($V_{ref+} - V_{ref-}$); however, the electrical specifications are no longer applicable.
6. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
7. Zero-scale error is the difference between 0000000000 and the converted output for zero input voltage; full-scale error is the difference between 1111111111 and the converted output for full-scale input voltage.
8. Total unadjusted error comprises linearity, zero-scale, and full-scale errors.
9. Both the input address and the output codes are expressed in positive logic.
10. I/O CLOCK period = 1/(I/O CLOCK frequency) (see Figure 6).
11. Any transitions of \overline{CS} are recognized as valid only if the level is maintained for a setup time plus two falling edges of the internal clock (1.425 µs) after the transition.



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PARAMETER MEASUREMENT INFORMATION

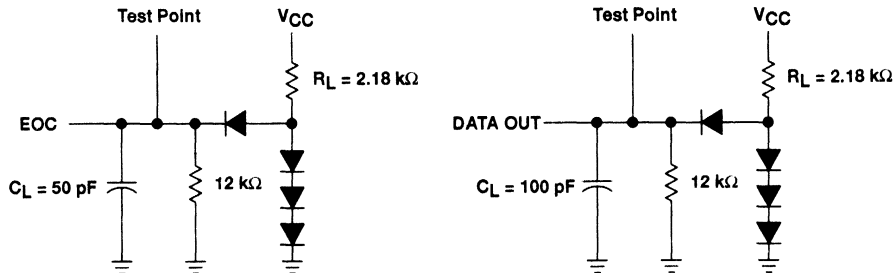


Figure 2. Load Circuits

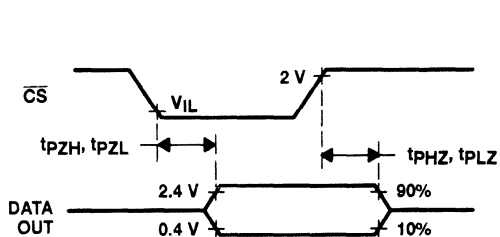


Figure 3. DATA OUT to Hi-Z Voltage Waveforms

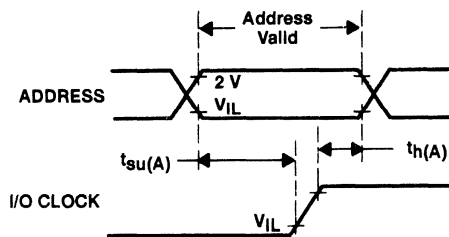


Figure 4. ADDRESS Setup Voltage Waveforms

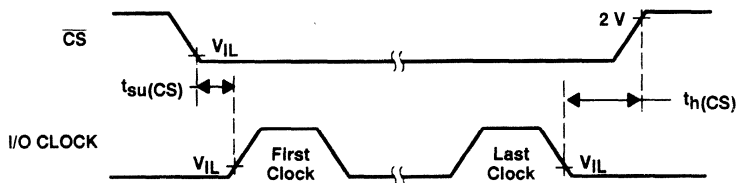


Figure 5. \overline{CS} and I/O CLOCK Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION

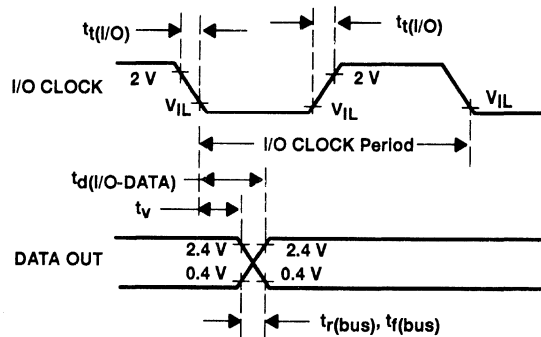


Figure 6. DATA OUT and I/O CLOCK Voltage Waveforms

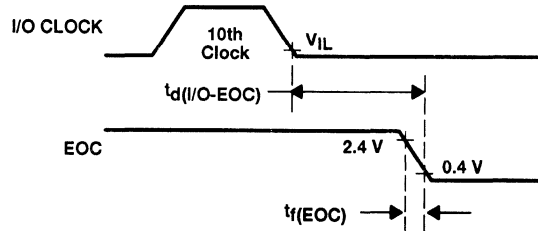


Figure 7. I/O CLOCK and EOC Voltage Waveforms

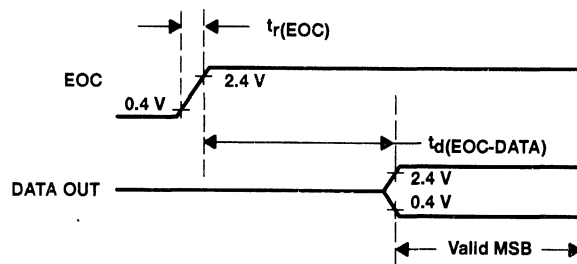


Figure 8. EOC and DATA OUT Voltage Waveforms

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WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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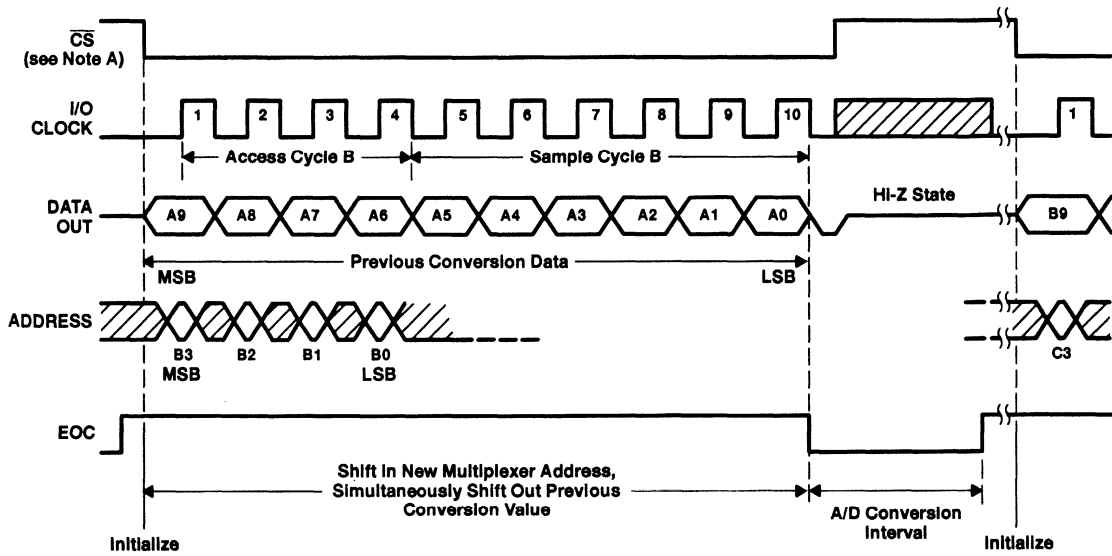


Figure 9. Timing for 10-Clock Transfer Using \overline{CS}

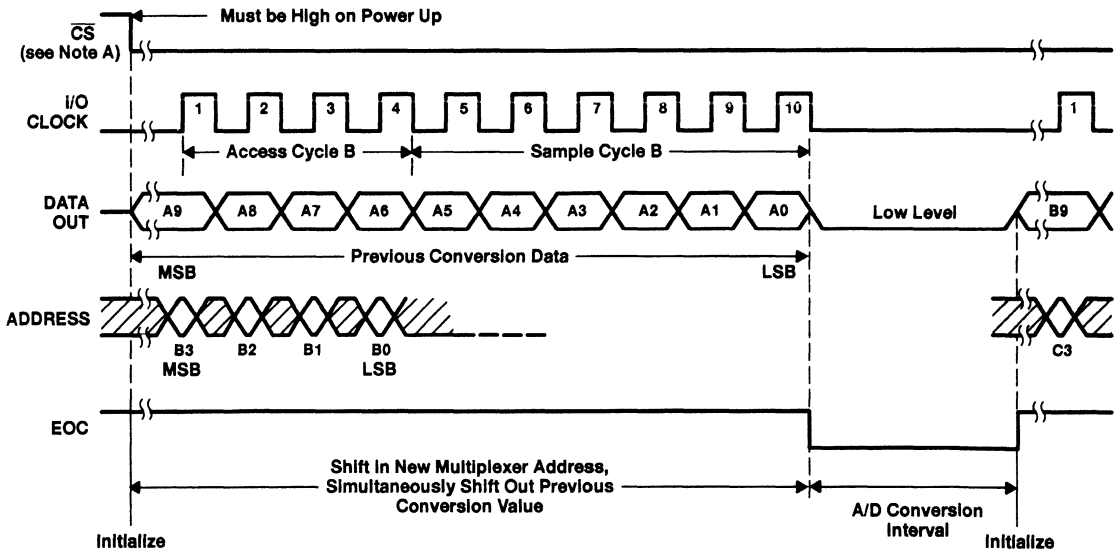


Figure 10. Timing for 10-Clock Transfer Not Using \overline{CS}

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to control input signals. No attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

TLV1543C, TLV1543M
3.3-V 10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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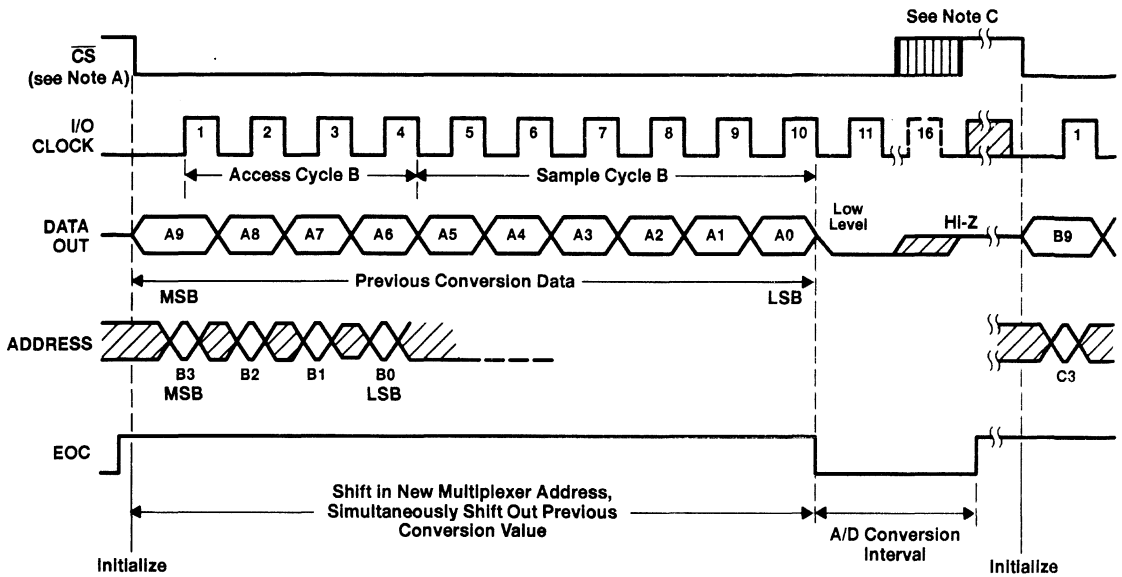


Figure 11. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Interval Shorter Than Conversion)

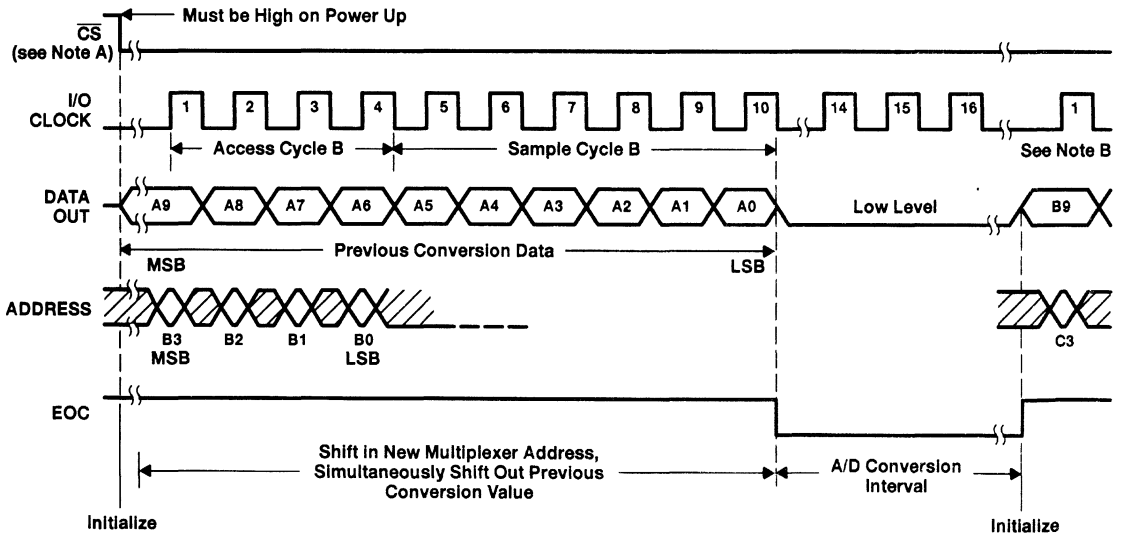


Figure 12. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Interval Shorter Than Conversion)

- NOTES:
- A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a set up time plus two falling edges of the internal system clock after \overline{CS} before responding to control input signals. No attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.
 - B. The first I/O CLOCK must occur after the rising edge of EOC.
 - C. A low-to-high transition of \overline{CS} disables ADDRESS and the I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock.

TLV1543C, TLV1543M
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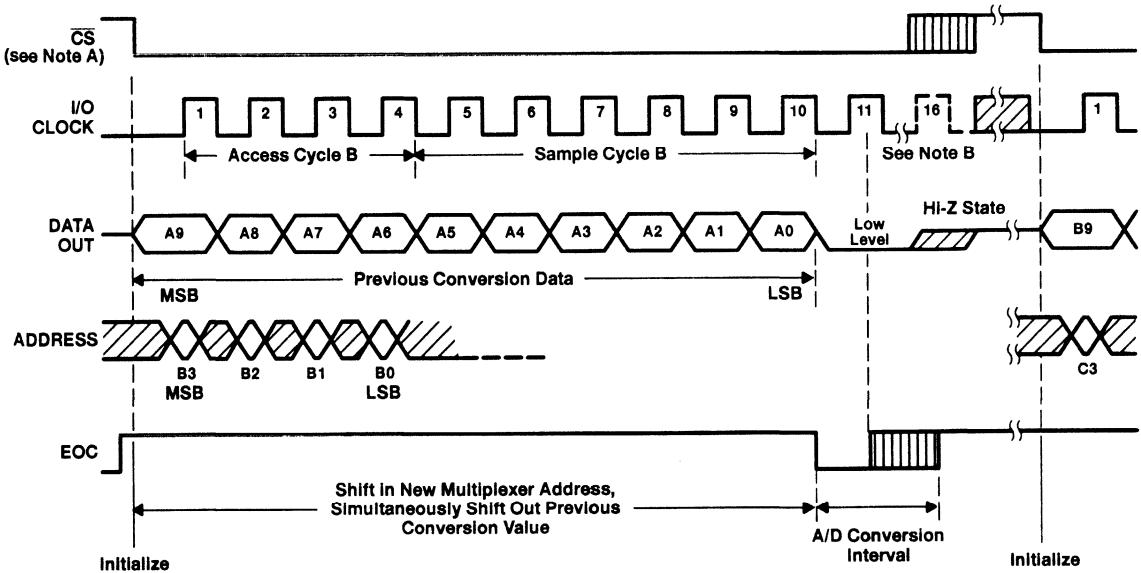


Figure 13. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Interval Longer Than Conversion)

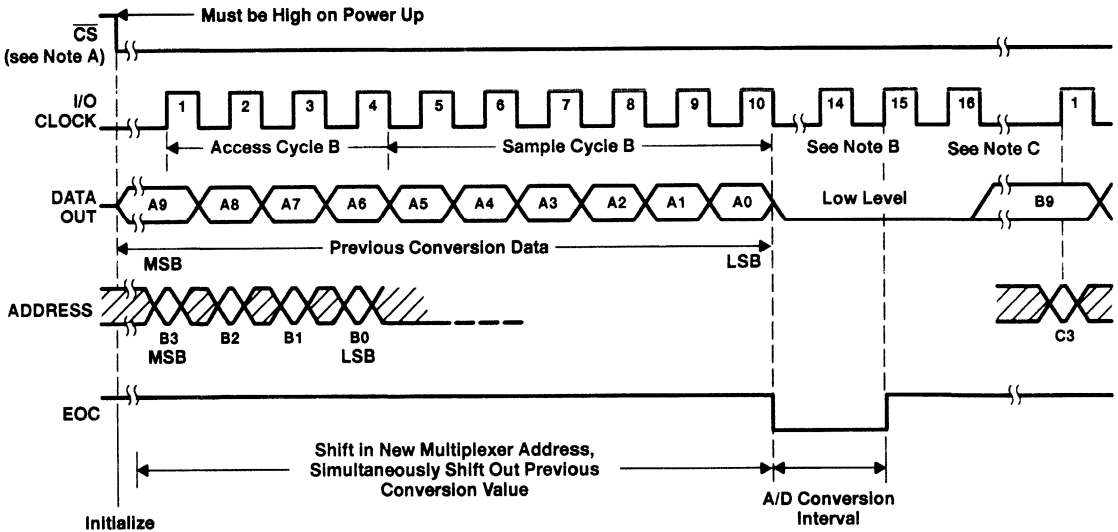


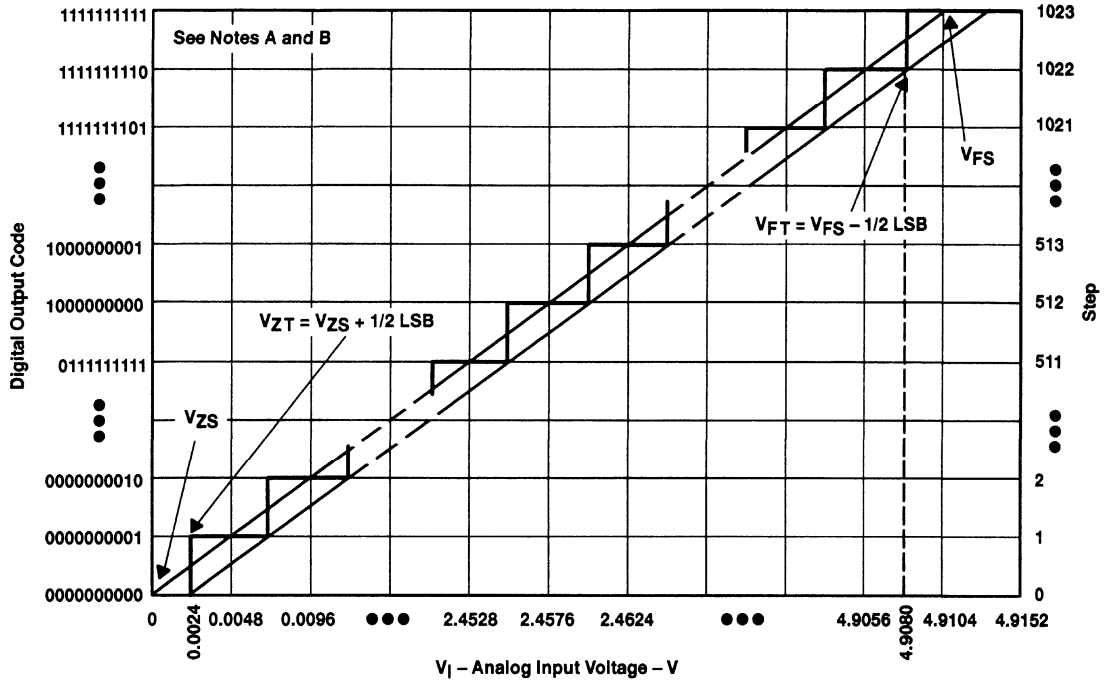
Figure 14. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Interval Longer Than Conversion)

- NOTES:
- A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a set up time plus two falling edges of the internal system clock after \overline{CS} before responding to control input signals. No attempt should be made to clock in an address until the minimum chip \overline{CS} setup time has elapsed.
 - B. The eleventh rising edge of the I/O CLOCK sequence must occur before the conversion is complete to prevent losing serial interface synchronization.
 - C. The I/O CLOCK sequence is exactly 16 clock pulses long.

TLV1543C, TLV1543M
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APPLICATION INFORMATION



- NOTES: A. This curve is based on the assumption that V_{ref+} and V_{ref-} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 0.0024 V and the transition to full scale (V_{FT}) is 4.908 V. 1 LSB = 4.8 mV.
 B. The full-scale value (V_{FS}) is the step whose nominal midstep value has the highest absolute value. The zero-scale value (V_{ZS}) is the step whose nominal midstep value equals zero.

Figure 15. Ideal Conversion Characteristics

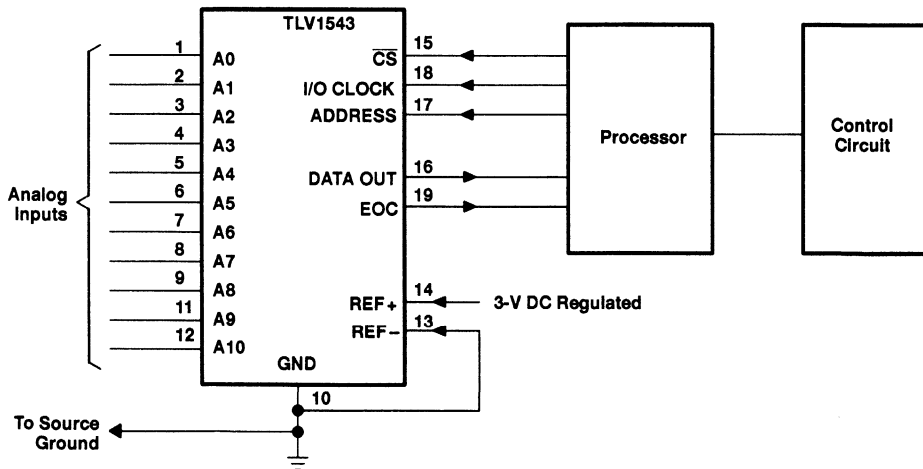


Figure 16. Serial Interface

APPLICATION INFORMATION

simplified analog input analysis

Using the equivalent circuit in Figure 17, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c/R_t C_i}\right) \quad (1)$$

where

$$R_t = R_S + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/2048) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/2048) = V_S \left(1 - e^{-t_c/R_t C_i}\right) \quad (3)$$

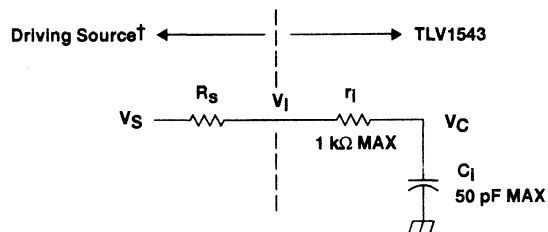
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(2048) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_S + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(2048) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_I = Input Voltage at A0–A10
 V_S = External Driving Source Voltage
 R_S = Source Resistance
 r_i = Input Resistance
 C_i = Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_S must be real at the input frequency.

Figure 17. Equivalent Input Circuit Including the Driving Source

TLV1549C, TLV1549I, TLV1549M 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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- 3.3-V Supply Operation
- 10-Bit-Resolution Analog-to-Digital Converter (ADC)
- Inherent Sample and Hold Function
- Total Unadjusted Error . . . ± 1 LSB Max
- On-Chip System Clock
- Terminal Compatible With TLC1549 and TLC1549x
- Application Report Available†
- CMOS Technology

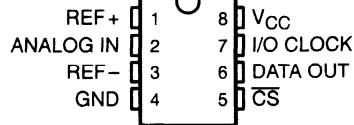
description

The TLV1549C, TLV1549I, and TLV1549M are 10-bit, switched-capacitor, successive-approximation, analog-to-digital converters. The devices have two digital inputs and a 3-state output [chip select (\overline{CS}), input-output clock (I/O CLOCK), and data output (DATA OUT)] that provide a three-wire interface to the serial port of a host processor.

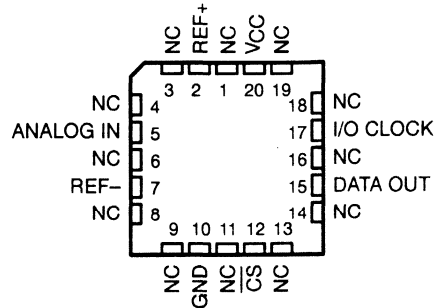
The sample-and-hold function is automatic. The converter incorporated in the device features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating free-air temperature range.

The TLV1549C is characterized for operation from 0°C to 70°C. The TLV1549I is characterized for operation from -40°C to 85°C. The TLV1549M is characterized for operation over the full military temperature range of -55°C to 125°C.

D, JG, OR P PACKAGE
(TOP VIEW)



FK PACKAGE
(TOP VIEW)



NC – No internal connection

AVAILABLE OPTIONS

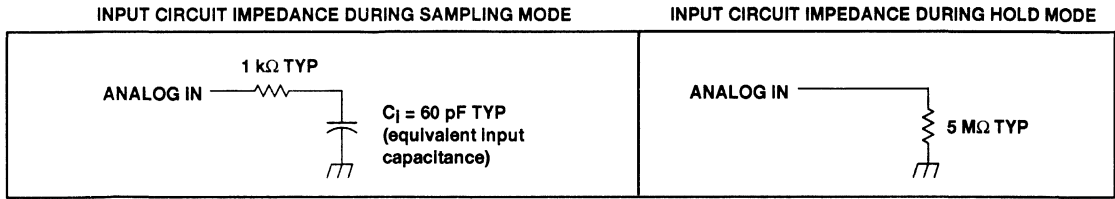
T _A	PACKAGE			
	SMALL OUTLINE (D)	CHIP CARRIER (FK)	CERAMIC DIP (JG)	PLASTIC DIP (P)
0°C to 70°C	TLV1549CD	—	—	TLV1549CP
-40°C to 85°C	TLV1549ID	—	—	TLV1549IP
-55°C to 125°C	—	TLV1549MFK	TLV1549MJG	—

† Interfacing the TLV1549 10-Bit Serial-Out ADC to Popular 3.3-V Microcontrollers (SLAA005)

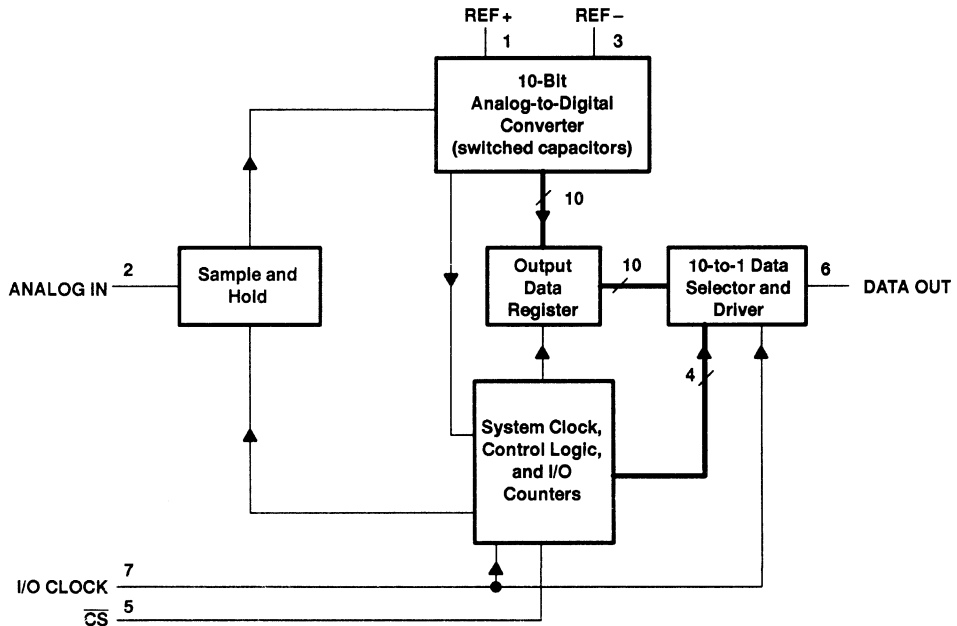
TLV1549C, TLV1549I, TLV1549M 10-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL

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typical equivalent inputs



functional block diagram



Terminal numbers shown are for the D, JG, and P packages only.

TLV1549C, TLV1549I, TLV1549M
10-BIT ANALOG-TO-DIGITAL CONVERTERS
WITH SERIAL CONTROL

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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANALOG IN	2	I	Analog input. The driving source impedance should be $\leq 1 \text{ k}\Omega$. The external driving source to ANALOG IN should have a current capability $\geq 10 \text{ mA}$.
$\overline{\text{CS}}$	5	I	Chip select. A high-to-low transition on $\overline{\text{CS}}$ resets the internal counters and controls and enables DATA OUT and I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock. A low-to-high transition disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.
DATA OUT	6	O	This 3-state serial output for the A/D conversion result is in the high-impedance state when $\overline{\text{CS}}$ is high and active when $\overline{\text{CS}}$ is low. With a valid chip select, DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB value of the previous conversion result. The next falling edge of I/O CLOCK drives DATA OUT to the logic level corresponding to the next most significant bit, and the remaining bits are shifted out in order with the LSB appearing on the ninth falling edge of I/O CLOCK. On the tenth falling edge of I/O CLOCK, DATA OUT is driven to a low logic level so that serial interface data transfers of more than ten clocks produce zeroes as the unused LSBs.
GND	4	I	The ground return for internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.
I/O CLOCK	7	I	The input/output clock receives the serial I/O CLOCK input and performs the following three functions: 1) On the third falling edge of I/O CLOCK, the analog input voltage begins charging the capacitor array and continues to do so until the tenth falling edge of I/O CLOCK. 2) It shifts the nine remaining bits of the previous conversion data out on DATA OUT. 3) It transfers control of the conversion to the internal state controller on the falling edge of the tenth clock.
REF +	1	I	The upper reference voltage value (nominally V_{CC}) is applied to REF +. The maximum input voltage range is determined by the difference between the voltage applied to REF + and the voltage applied to REF –.
REF –	3	I	The lower reference voltage value (nominally ground) is applied to this REF –.
V_{CC}	8	I	Positive supply voltage

detailed description

With chip select ($\overline{\text{CS}}$) inactive (high), the I/O CLOCK input is initially disabled and DATA OUT is in the high-impedance state. When the serial interface takes $\overline{\text{CS}}$ active (low), the conversion sequence begins with the enabling of I/O CLOCK and the removal of DATA OUT from the high-impedance state. The serial interface then provides the I/O CLOCK sequence to I/O CLOCK and receives the previous conversion result from DATA OUT. I/O CLOCK receives an input sequence that is between 10 and 16 clocks long from the host serial interface. The first ten I/O clocks provide the control timing for sampling the analog input.

There are six basic serial interface timing modes that can be used with the TLV1549. These modes are determined by the speed of I/O CLOCK and the operation of $\overline{\text{CS}}$ as shown in Table 1. These modes are: (1) a fast mode with a 10-clock transfer and $\overline{\text{CS}}$ inactive (high) between transfers, (2) a fast mode with a 10-clock transfer and $\overline{\text{CS}}$ active (low) continuously, (3) a fast mode with an 11- to 16-clock transfer and $\overline{\text{CS}}$ inactive (high) between transfers, (4) a fast mode with a 16-bit transfer and $\overline{\text{CS}}$ active (low) continuously, (5) a slow mode with an 11- to 16-clock transfer and $\overline{\text{CS}}$ inactive (high) between transfers, and (6) a slow mode with a 16-clock transfer and $\overline{\text{CS}}$ active (low) continuously.

The MSB of the previous conversion appears on DATA OUT on the falling edge of $\overline{\text{CS}}$ in mode 1, mode 3, and mode 5, within 21 μs from the falling edge of the tenth I/O CLOCK in mode 2 and mode 4, and following the 16th clock falling edge in mode 6. The remaining nine bits are shifted out on the next nine falling edges of the I/O CLOCK. Ten bits of data are transmitted to the host serial interface through DATA OUT. The number of serial clock pulses used also depends on the mode of operation, but a minimum of ten clock pulses is required for conversion to begin. On the tenth clock falling edge, the internal logic takes DATA OUT low to ensure that the remaining bit values are zero if the I/O CLOCK transfer is more than ten clocks long.

Table 1 lists the operational modes with respect to the state of $\overline{\text{CS}}$, the number of I/O serial transfer clocks that can be used, and the timing on which the MSB of the previous conversion appears at the output.



TLV1549C, TLV1549I, TLV1549M

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Table 1. Mode Operation

MODES		\overline{CS}	NO. OF I/O CLOCKS	MSB AT DATA OUT†	TIMING DIAGRAM
Fast Modes	Mode 1	High between conversion cycles	10	\overline{CS} falling edge	Figure 6
	Mode 2	Low continuously	10	Within 21 μ s	Figure 7
	Mode 3	High between conversion cycles	11 to 16‡	\overline{CS} falling edge	Figure 8
	Mode 4	Low continuously	16‡	Within 21 μ s	Figure 9
Slow Modes	Mode 5	High between conversion cycles	11 to 16‡	\overline{CS} falling edge	Figure 10
	Mode 6	Low continuously	16‡	16th clock falling edge	Figure 11

† This timing also initiates serial-interface communication.

‡ No more than 16 clocks should be used.

All the modes require a minimum period of 21 μ s after the falling edge of the tenth I/O CLOCK before a new transfer sequence can begin. During a serial I/O CLOCK data transfer, \overline{CS} must be active (low) so that the I/O CLOCK input is enabled. When \overline{CS} is toggled between data transfers (modes 1, 3, and 5), the transitions at \overline{CS} are recognized as valid only if the level is maintained for a minimum period of 1.425 μ s after the transition. If the transfer is more than ten I/O clocks (modes 3, 4, 5, and 6), the rising edge of the eleventh clock must occur within 9.5 μ s after the falling edge of the tenth I/O CLOCK; otherwise, the device could lose synchronization with the host serial interface and \overline{CS} has to be toggled to restore proper operation.

fast modes

The device is in a fast mode when the serial I/O CLOCK data transfer is completed within 21 μ s from the falling edge of the tenth I/O CLOCK. With a 10-clock serial transfer, the device can only run in a fast mode.

mode 1: fast mode, \overline{CS} inactive (high) between transfers, 10-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O-CLOCK transfers and each transfer is ten clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.

mode 2: fast mode, \overline{CS} active (low) continuously, 10-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O-CLOCK transfers and each transfer is ten clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. Within 21 μ s after the falling edge of the tenth I/O CLOCK, the MSB of the previous conversion appears at DATA OUT.

mode 3: fast mode, \overline{CS} inactive (high) between transfers, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O-CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.

mode 4: fast mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O-CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. Within 21 μ s after the falling edge of the tenth I/O CLOCK, the MSB of the previous conversion appears at DATA OUT.

slow modes

In a slow mode, the serial I/O CLOCK data transfer is completed after 21 μ s from the falling edge of the tenth I/O CLOCK.



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mode 5: slow mode, \overline{CS} inactive (high) between transfers, 11- to 16-clock transfer

In this mode, \overline{CS} is inactive (high) between serial I/O-CLOCK transfers and each transfer can be 11 to 16 clocks long. The falling edge of \overline{CS} begins the sequence by removing DATA OUT from the high-impedance state. The rising edge of \overline{CS} ends the sequence by returning DATA OUT to the high-impedance state within the specified delay time. Also, the rising edge of \overline{CS} disables I/O CLOCK within a setup time plus two falling edges of the internal system clock.

mode 6: slow mode, \overline{CS} active (low) continuously, 16-clock transfer

In this mode, \overline{CS} is active (low) between serial I/O-CLOCK transfers and each transfer must be exactly 16 clocks long. After the initial conversion cycle, \overline{CS} is held active (low) for subsequent conversions. The falling edge of the sixteenth I/O CLOCK then begins each sequence by removing DATA OUT from the low state, allowing the MSB of the previous conversion to appear immediately at DATA OUT. The device is then ready for the next 16-clock transfer initiated by the serial interface.

analog input sampling

Sampling of the analog input starts on the falling edge of the third I/O CLOCK, and sampling continues for seven I/O CLOCK periods. The sample is held on the falling edge of the tenth I/O CLOCK.

converter and analog input

The CMOS threshold detector in the successive-approximation conversion system determines each bit by examining the charge on a series of binary-weighted capacitors (see Figure 1). In the first phase of the conversion process, the analog input is sampled by closing the S_C switch and all S_T switches simultaneously. This action charges all the capacitors to the input voltage.

In the next phase of the conversion process, all S_T and S_C switches are opened and the threshold detector begins identifying bits by identifying the charge (voltage) on each capacitor relative to the reference (REF-) voltage. In the switching sequence, ten capacitors are examined separately until all ten bits are identified and then the charge-convert sequence is repeated. In the first step of the conversion phase, the threshold detector looks at the first capacitor (weight = 512). Node 512 of this capacitor is switched to the REF+ voltage, and the equivalent nodes of all the other capacitors on the ladder are switched to REF-. If the voltage at the summing node is greater than the trip point of the threshold detector (approximately one-half V_{CC}), a bit 0 is placed in the output register and the 512-weight capacitor is switched to REF-. If the voltage at the summing node is less than the trip point of the threshold detector, a bit 1 is placed in the register and this 512-weight capacitor remains connected to REF+ through the remainder of the successive-approximation process. The process is repeated for the 256-weight capacitor, the 128-weight capacitor, and so forth down the line until all bits are determined.

With each step of the successive-approximation process, the initial charge is redistributed among the capacitors. The conversion process relies on charge redistribution to determine the bits from MSB to LSB.

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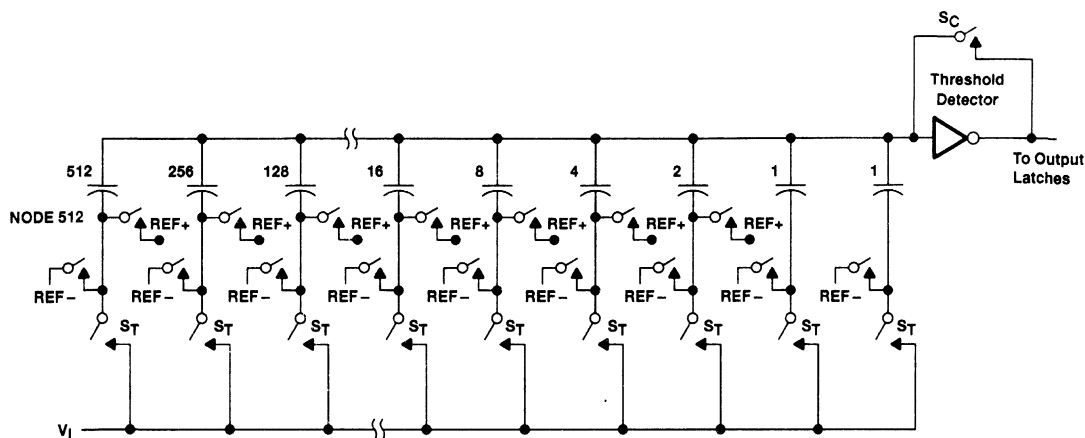


Figure 1. Simplified Model of the Successive-Approximation System

chip-select operation

The trailing edge of \overline{CS} starts all modes of operation, and \overline{CS} can abort a conversion sequence in any mode. A high-to-low transition on \overline{CS} within the specified time during an ongoing cycle aborts the cycle, and the device returns to the initial state (the contents of the output data register remain at the previous conversion result). Exercise care to prevent \overline{CS} from being taken low close to completion of conversion because the output data may be corrupted.

reference voltage inputs

There are two reference inputs used with the TLV1549: REF+ and REF-. These voltage values establish the upper and lower limits of the analog input to produce a full-scale and zero reading, respectively. The values of REF+, REF-, and the analog input should not exceed the positive supply or be lower than GND consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF+ and at zero when the input signal is equal to or lower than REF-.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage range, V_{CC} (see Note 1):	TLV1549C	-0.5 V to 6.5 V
	TLV1549I	-0.5 V to 6.5 V
	TLV1549M	-0.5 V to 6 V
Input voltage range, V_I (any input)		-0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O		-0.3 V to $V_{CC} + 0.3$ V
Positive reference voltage, V_{ref+}		$V_{CC} + 0.1$ V
Negative reference voltage, V_{ref-}		-0.1 V
Peak input current (any input)		± 20 mA
Peak total input current (all inputs)		± 30 mA
Operating free-air temperature range, T_A :	TLV1549C	0°C to 70°C
	TLV1549I	-40°C to 85°C
	TLV1549M	-55°C to 125°C
Storage temperature range, T_{stg}		-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds		260°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to ground with REF- and GND wired together (unless otherwise noted).



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recommended operating conditions

		MIN	NOM	MAX	UNIT	
Supply voltage, V_{CC}		3	3.3	3.6	V	
Positive reference voltage, V_{ref+} (see Note 2)		V_{CC}			V	
Negative reference voltage, V_{ref-} (see Note 2)		0			V	
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)		2.5	V_{CC}	$V_{CC} + 0.2$	V	
Analog input voltage (see Note 2)		0			V_{CC}	
High-level control input voltage, V_{IH}	$V_{CC} = 3\text{ V to }3.6\text{ V}$	2			V	
Low-level control input voltage, V_{IL}	$V_{CC} = 3\text{ V to }3.6\text{ V}$	0.6			V	
Clock frequency at I/O CLOCK (see Note 3)		0			2.1	MHz
Setup time, \overline{CS} low before first I/O CLOCK \uparrow , $t_{su}(CS)$ (see Note 4)		1.425			μs	
Hold time, \overline{CS} low after last I/O CLOCK \downarrow , $t_h(CS)$		0			ns	
Pulse duration, I/O CLOCK high, $t_{WH}(I/O)$		190			ns	
Pulse duration, I/O CLOCK low, $t_{WL}(I/O)$		190			ns	
Transition time, I/O CLOCK, $t_{(I/O)}$ (see Note 5 and Figure 5)					1	μs
Transition time, \overline{CS} , $t_{(CS)}$					10	μs
Operating free-air temperature, T_A	TLV1549C	0			70	$^{\circ}\text{C}$
	TLV1549I	-40			85	$^{\circ}\text{C}$
	TLV1549M	-55			125	$^{\circ}\text{C}$

- NOTES: 2. Analog input voltages greater than that applied to REF + convert as all ones (1111111111), while input voltages less than that applied to REF - convert as all zeros (0000000000). The TLV1549 is functional with reference voltages down to 1 V ($V_{ref+} - V_{ref-}$); however, the electrical specifications are no longer applicable.
3. For 11- to 16-bit transfers, after the tenth I/O CLOCK falling edge ($\leq 2\text{ V}$), at least one I/O CLOCK rising edge ($\geq 2\text{ V}$) must occur within 9.5 μs .
4. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to the I/O CLOCK. Therefore, no attempt should be made to clock out the data until the minimum \overline{CS} setup time has elapsed.
5. This is the time required for the clock input signal to fall from V_{IHmin} to V_{ILmax} or to rise from V_{ILmax} to V_{IHmin} . In the vicinity of normal room temperature, the device functions with input clock transition time as slow as 1 μs for remote data-acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 3\text{ V to }3.6\text{ V}$, I/O CLOCK frequency = 2.1 MHz (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
V_{OH}	High-level output voltage	$V_{CC} = 3\text{ V}$, $I_{OH} = -1.6\text{ mA}$	2.4			V	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$, $I_{OH} = -20\text{ }\mu\text{A}$	$V_{CC} - 0.1$				
V_{OL}	Low-level output voltage	$V_{CC} = 3\text{ V}$, $I_{OL} = 1.6\text{ mA}$			0.4	V	
		$V_{CC} = 3\text{ V to }3.6\text{ V}$, $I_{OL} = 20\text{ }\mu\text{A}$			0.1		
I_{OZ}	Off-state (high-impedance-state) output current	$V_O = V_{CC}$, \overline{CS} at V_{CC}			10	μA	
		$V_O = 0$, \overline{CS} at V_{CC}			-10		
I_{IH}	High-level input current	$V_I = V_{CC}$	0.005		2.5	μA	
I_{IL}	Low-level input current	$V_I = 0$	-0.005		-2.5	μA	
I_{CC}	Operating supply current	\overline{CS} at 0 V	0.4		2.5	mA	
Analog input leakage current		$V_I = V_{CC}$			1	μA	
		$V_I = 0$			-1		
Maximum static analog reference current into REF+		$V_{ref+} = V_{CC}$, $V_{ref-} = \text{GND}$			10	μA	
C_i	Input capacitance	TLV1549C, I (Analog)	During sample cycle		30	55	pF
		TLV1549M, (Analog)	During sample cycle		30		
		TLV1549C, I (Control)			5	15	
		TLV1549M, (Control)			5		

† All typical values are at $V_{CC} = 3.3\text{ V}$, $T_A = 25^\circ\text{C}$.

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**operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 3\text{ V to }3.6\text{ V}$, I/O CLOCK frequency = 2.1 MHz**

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
	Linearity error (see Note 6)			± 1	LSB
	Zero error (see Note 7)	See Note 2		± 1	LSB
	Full-scale error (see Note 7)	See Note 2		± 1	LSB
	Total unadjusted error (see Note 8)			± 1	LSB
t_{conv}	Conversion time	See Figures 6–11		21	μs
t_c	Total cycle time (access, sample, and conversion)	See Figures 6–11 and Note 9		21 + 10 I/O CLOCK periods	μs
t_v	Valid time, DATA OUT remains valid after I/O CLOCK \downarrow	See Figure 5	10		ns
$t_{d(I/O-DATA)}$	Delay time, I/O CLOCK \downarrow to DATA OUT valid	See Figure 5		240	ns
t_{PZH}, t_{PZL}	Enable time, $\overline{CS}\downarrow$ to DATA OUT (MSB driven)	See Figure 3		1.3	μs
t_{PHZ}, t_{PLZ}	Disable time, $\overline{CS}\uparrow$ to DATA OUT (high impedance)	See Figure 3		180	ns
$t_r(\text{bus})$	Rise time, data bus	See Figure 5		300	ns
$t_f(\text{bus})$	Fall time, data bus	See Figure 5		300	ns
$t_{d(I/O-CS)}$	Delay time, 10th I/O CLOCK \downarrow to $\overline{CS}\downarrow$ to abort conversion (see Note 10)			9	μs

- NOTES: 2. Analog input voltages greater than that applied to REF + convert as all ones (1111111111), while input voltages less than that applied to REF – convert as all zeros (0000000000). The device is functional with reference voltages down to 1 V ($V_{ref+} - V_{ref-}$); however, the electrical specifications are no longer applicable.
6. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
7. Zero error is the difference between 0000000000 and the converted output for zero input voltage; full-scale error is the difference between 1111111111 and the converted output for full-scale input voltage.
8. Total unadjusted error comprises linearity, zero, and full-scale errors.
9. I/O CLOCK period = 1/(I/O CLOCK frequency). Sampling begins on the falling edge of the third I/O CLOCK, continues for seven I/O CLOCK periods, and ends on the falling edge of the tenth I/O CLOCK (see Figure 5).
10. Any transitions of \overline{CS} are recognized as valid only if the level is maintained for a minimum of a setup time plus two falling edges of the internal clock (1.425 μs) after the transition.

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PARAMETER MEASUREMENT INFORMATION

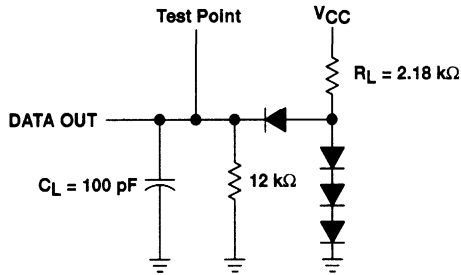


Figure 2. Load Circuit

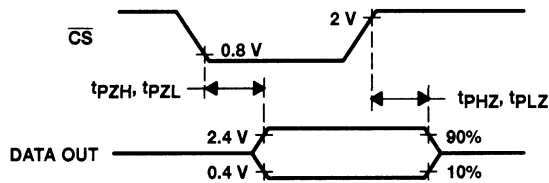


Figure 3. DATA OUT to Hi-Z Voltage Waveforms

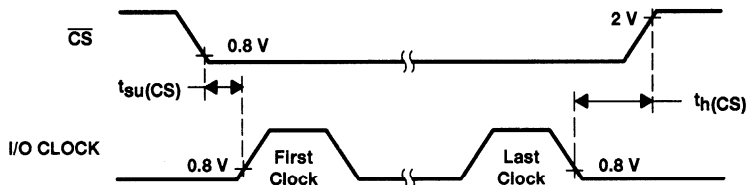


Figure 4. CS to I/O CLOCK Voltage Waveforms

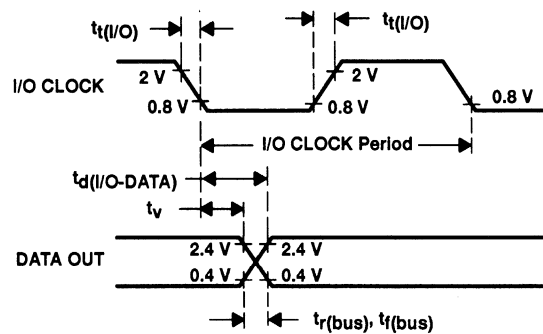


Figure 5. I/O CLOCK and DATA OUT Voltage Waveforms

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PARAMETER MEASUREMENT INFORMATION

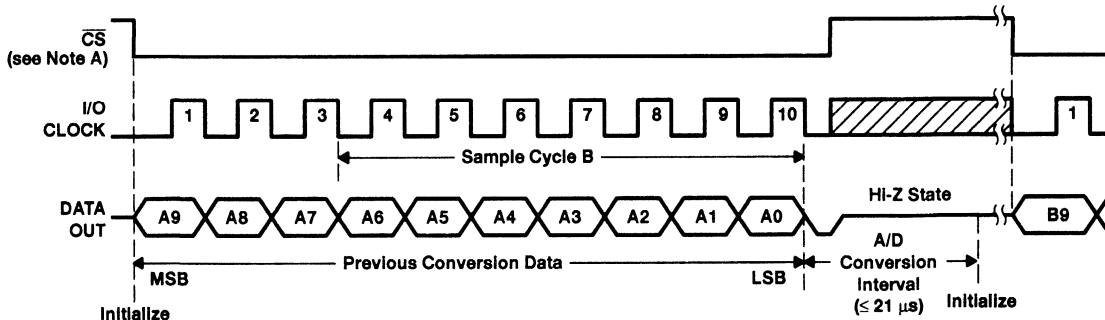


Figure 6. Timing for 10-Clock Transfer Using \overline{CS}

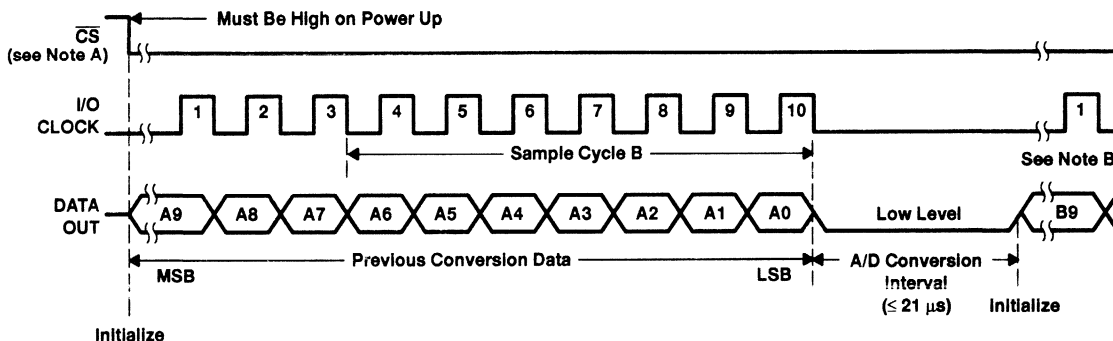


Figure 7. Timing for 10-Clock Transfer Not Using \overline{CS}

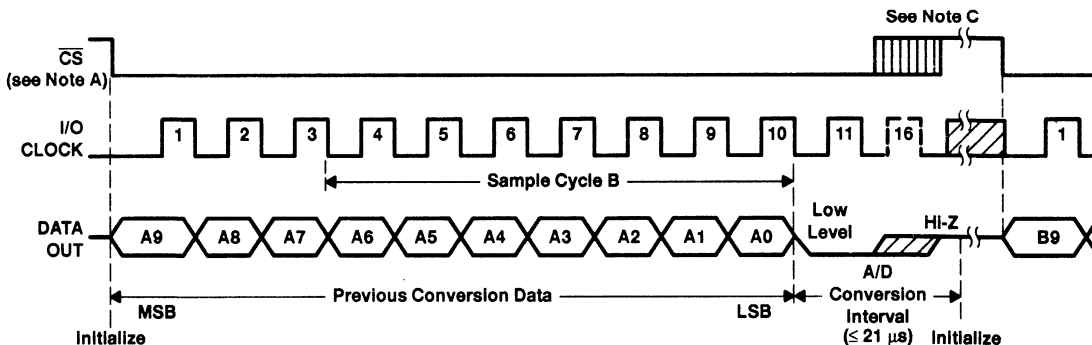


Figure 8. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Completed Within 21 μ s)

- NOTES:
- A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to the I/O CLOCK. No attempt should be made to clock out the data until the minimum \overline{CS} setup time has elapsed.
 - B. A low-to-high transition of \overline{CS} disables I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock.
 - C. The first I/O CLOCK must occur after the end of the previous conversion.

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PARAMETER MEASUREMENT INFORMATION

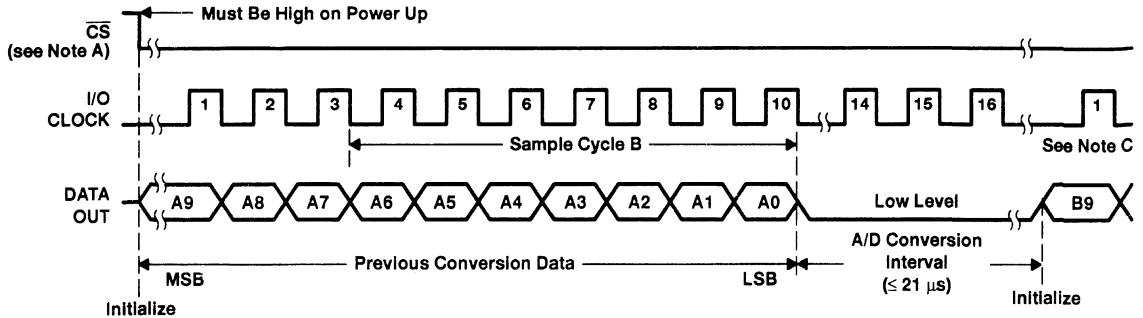


Figure 9. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Completed Within 21 μ s)

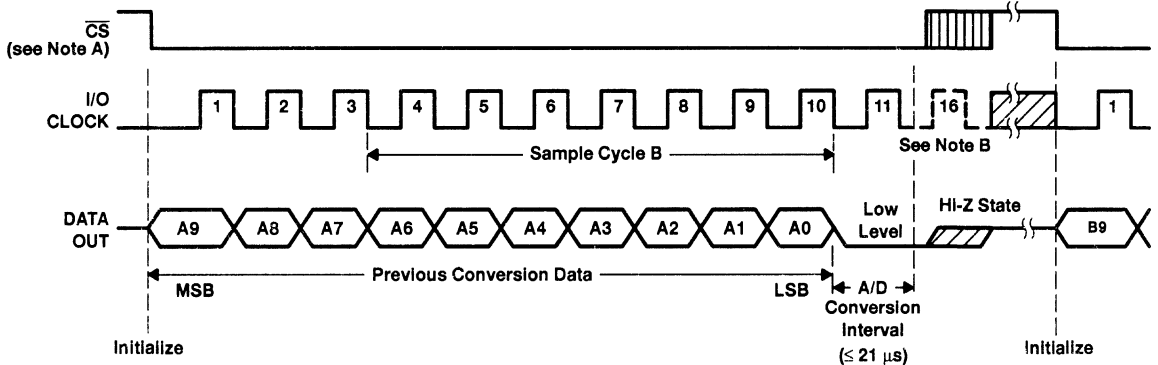


Figure 10. Timing for 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Completed After 21 μ s)

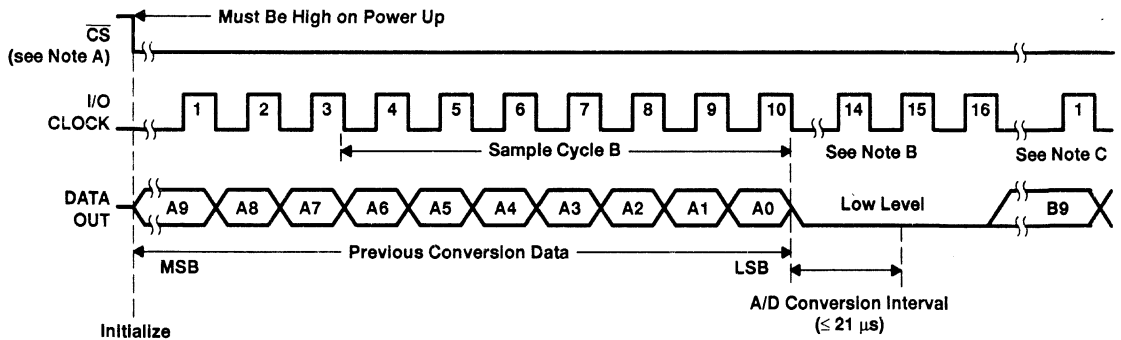


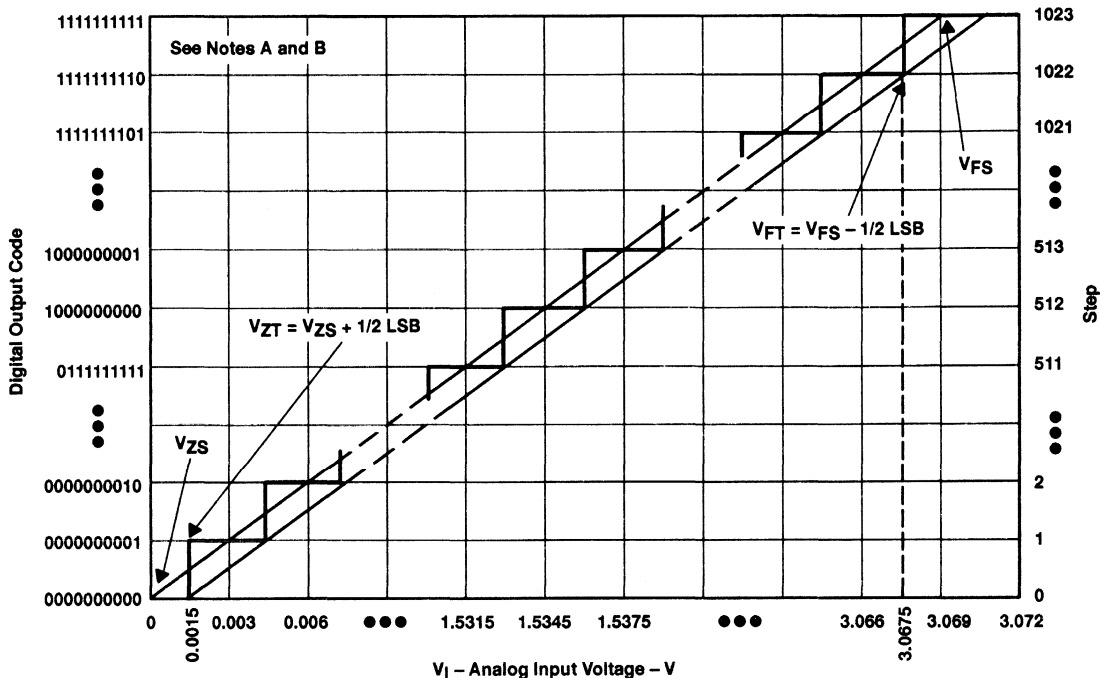
Figure 11. Timing for 16-Clock Transfer Not Using \overline{CS} (Serial Transfer Completed After 21 μ s)

- NOTES:
- A. To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a set up time plus two falling edges of the internal system clock after $\overline{CS}\downarrow$ before responding to the I/O CLOCK. No attempt should be made to clock out the data until the minimum \overline{CS} setup time has elapsed.
 - B. A low-to-high transition of \overline{CS} disables I/O CLOCK within a maximum of a setup time plus two falling edges of the internal system clock.
 - C. The first I/O CLOCK must occur after the end of the previous conversion.

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APPLICATION INFORMATION



- NOTES: A. This curve is based on the assumption that V_{ref+} and V_{ref-} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 0.0015 V and the transition to full scale (V_{FT}) is 3.0675 V. 1 LSB = 3 mV.
 B. The full-scale value (V_{FS}) is the step whose nominal midstep value has the highest absolute value. The zero-scale value (V_{ZS}) is the step whose nominal midstep value equals zero.

Figure 12. Ideal Conversion Characteristics

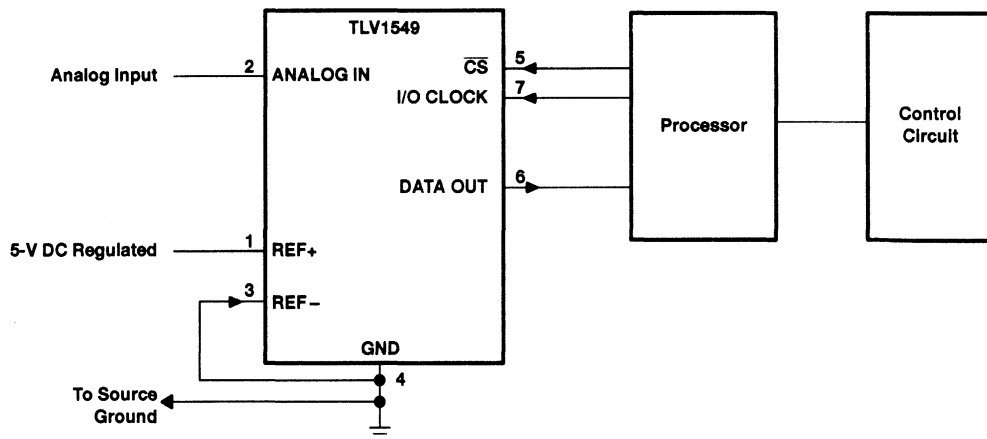


Figure 13. Typical Serial Interface

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simplified analog input analysis

Using the equivalent circuit in Figure 14, the time required to charge the analog input capacitance from 0 to V_S within 1/2 LSB can be derived as follows:

The capacitance charging voltage is given by

$$V_C = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (1)$$

where

$$R_t = R_s + r_i$$

The final voltage to 1/2 LSB is given by

$$V_C (1/2 \text{ LSB}) = V_S - (V_S/2048) \quad (2)$$

Equating equation 1 to equation 2 and solving for time t_c gives

$$V_S - (V_S/2048) = V_S \left(1 - e^{-t_c / R_t C_i} \right) \quad (3)$$

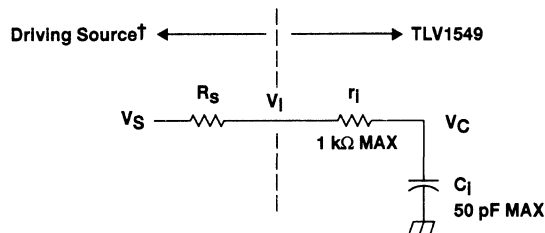
and

$$t_c (1/2 \text{ LSB}) = R_t \times C_i \times \ln(2048) \quad (4)$$

Therefore, with the values given the time for the analog input signal to settle is

$$t_c (1/2 \text{ LSB}) = (R_s + 1 \text{ k}\Omega) \times 60 \text{ pF} \times \ln(2048) \quad (5)$$

This time must be less than the converter sample time shown in the timing diagrams.



V_i = Input Voltage at ANALOG IN
 V_S = External Driving Source Voltage
 R_s = Source Resistance
 r_i = Input Resistance
 C_i = Equivalent Input Capacitance

† Driving source requirements:

- Noise and distortion for the source must be equivalent to the resolution of the converter.
- R_s must be real at the input frequency.

Figure 14. Equivalent Input Circuit Including the Driving Source

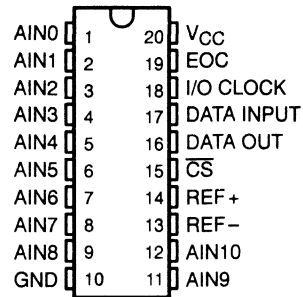
TLV2543C, TLV2543I

12-BIT ANALOG-TO-DIGITAL CONVERTERS WITH SERIAL CONTROL AND 11 ANALOG INPUTS

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- 12-Bit-Resolution A/D Converter
- 10- μ s Conversion Time Over Operating Temperature
- 11 Analog Input Channels
- 3 Built-In Self-Test Modes
- Inherent Sample and Hold
- Linearity Error . . . ± 1 LSB Max
- On-Chip System Clock
- End-of-Conversion (EOC) Output
- Unipolar or Bipolar Output Operation (Signed Binary With Respect 1/2 the Applied Referenced Voltage)
- Programmable MSB or LSB First
- Programmable Power Down
- Programmable Output Data Length
- CMOS Technology

DB, DW, OR N PACKAGE
(TOP VIEW)



description

The TLV2543C and TLV2543I are 12-bit, switched-capacitor, successive-approximation, analog-to-digital converters (ADCs). Each device has three control inputs [chip select (\overline{CS}), the input-output clock (I/O CLOCK), and the address input (DATA INPUT)] and is designed for communication with the serial port of a host processor or peripheral through a serial 3-state output. The device allows high-speed data transfers from the host.

In addition to the high-speed converter and versatile control capability, the device has an on-chip 14-channel multiplexer that can select any one of 11 inputs or any one of three internal self-test voltages. The sample-and-hold function is automatic. At the end of conversion, the end-of-conversion (EOC) output goes high to indicate that conversion is complete. The converter incorporated in the device features differential high-impedance reference inputs that facilitate ratiometric conversion, scaling, and isolation of analog circuitry from logic and supply noise. A switched-capacitor design allows low-error conversion over the full operating temperature range.

The TLV2543 is available in the DW, FN, and N packages. The TLV2543C is characterized for operation from 0°C to 70°C, and the TLV2543I is characterized for operation from -40°C to 85°C.

AVAILABLE OPTIONS

T _A	PACKAGE		
	SMALL OUTLINE		PLASTIC DIP
	DW	DB†	N
0°C to 70°C	TLV2543CDW	TLV2543CDB	TLV2543CN
-40°C to 85°C	TLV2543IDW	TLV2543IDB	TLV2543IN

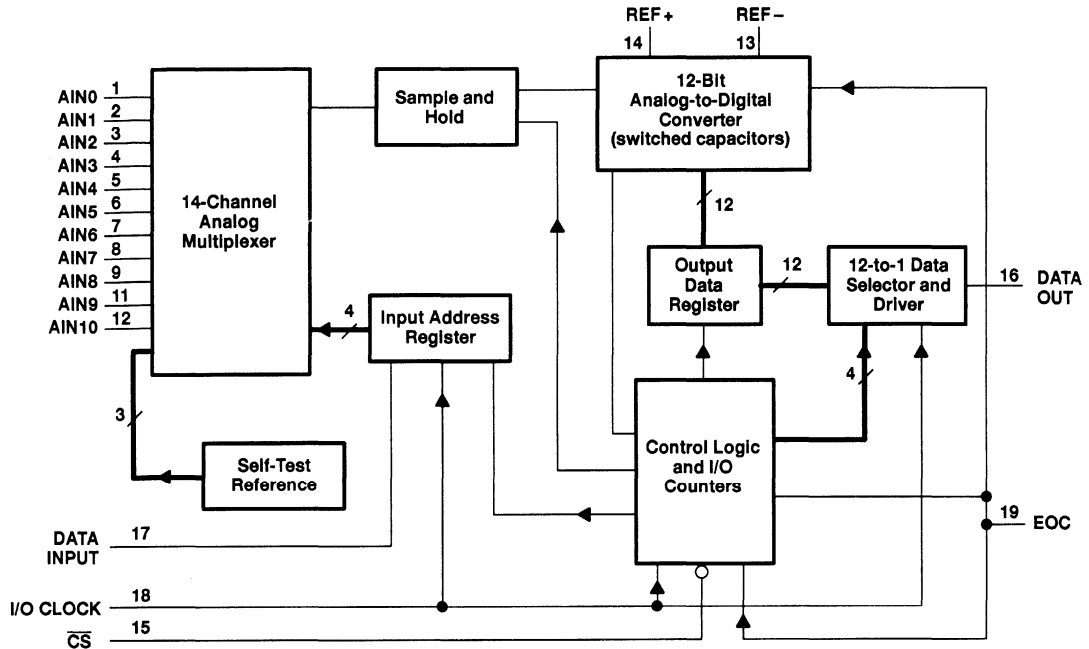
† Available in tape and reel and ordered as the TLV2543CDBR or TLV2543IDBR.

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functional block diagram



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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AIN0 – AIN10	1–9, 11, 12	I	These 11 analog-signal inputs are internally multiplexed. The driving source impedance should be less than or equal to 50 Ω for 4.1-MHz I/O CLOCK operation and capable of slewing the analog input voltage into a capacitance of 60 pF.
\overline{CS}	15	I	Chip select. A high-to-low transition on \overline{CS} resets the internal counters and controls and enables DATA OUT, DATA INPUT, and I/O CLOCK. A low-to-high transition disables DATA INPUT and I/O CLOCK within a setup time.
DATA INPUT	17	I	Serial-data input. A 4-bit serial address selects the desired analog input or test voltage to be converted next. The serial data is presented with the MSB first and is shifted in on the first four rising edges of I/O CLOCK. After the four address bits are read into the address register, I/O CLOCK clocks the remaining bits in order.
DATA OUT	16	O	The 3-state serial output for the A/D conversion result. DATA OUT is in the high-impedance state when \overline{CS} is high and active when \overline{CS} is low. With a valid \overline{CS} , DATA OUT is removed from the high-impedance state and is driven to the logic level corresponding to the MSB/LSB value of the previous conversion result. The next falling edge of I/O CLOCK drives DATA OUT to the logic level corresponding to the next MSB/LSB, and the remaining bits are shifted out in order.
EOC	19	O	End of conversion goes from a high to a low logic level after the falling edge of the last I/O CLOCK and remains low until the conversion is complete and data are ready for transfer.
GND	10		The ground return terminal for the internal circuitry. Unless otherwise noted, all voltage measurements are with respect to GND.
I/O CLOCK	18	I	Input/output clock. I/O CLOCK receives the serial input and performs the following four functions: 1. It clocks the eight input data bits into the input data register on the first eight rising edges of I/O CLOCK with the multiplexer address available after the fourth rising edge. 2. On the fourth falling edge of I/O CLOCK, the analog input voltage on the selected multiplexer input begins charging the capacitor array and continues to do so until the last falling edge of I/O CLOCK. 3. It shifts the 11 remaining bits of the previous conversion data out on DATA OUT. Data changes on the falling edge of I/O CLOCK. 4. It transfers control of the conversion to the internal state controller on the falling edge of the last I/O CLOCK.
REF+	14	I	The upper reference voltage value (nominally V_{CC}) is applied to REF+. The maximum input voltage range is determined by the difference between the voltage applied to this terminal and the voltage applied to the REF– terminal.
REF–	13	I	The lower reference voltage value (nominally ground) is applied to REF–.
V_{CC}	20		Positive supply voltage

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detailed description

Initially, with chip select (\overline{CS}) high, I/O CLOCK and DATA INPUT are disabled and DATA OUT is in the high-impedance state. \overline{CS} , going low, begins the conversion sequence by enabling I/O CLOCK and DATA INPUT and removes DATA OUT from the high-impedance state.

The input data is an 8-bit data stream consisting of a 4-bit analog channel address (D7–D4), a 2-bit data length select (D3–D2), an output MSB or LSB first bit (D1), and a unipolar or bipolar output select bit (D0) that are applied to DATA INPUT. The I/O CLOCK sequence applied to the I/O CLOCK terminal transfers this data to the input data register.

During this transfer, the I/O CLOCK sequence also shifts the previous conversion result from the output data register to DATA OUT. I/O CLOCK receives the input sequence of 8, 12, or 16 clocks long depending on the data-length selection in the input data register. Sampling of the analog input begins on the fourth falling edge of the input I/O CLOCK sequence and is held after the last falling edge of the I/O CLOCK sequence. The last falling edge of the I/O CLOCK sequence also takes EOC low and begins the conversion.



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converter operation

The operation of the converter is organized as a succession of two distinct cycles: 1) the I/O cycle and 2) the actual conversion cycle. The I/O cycle is defined by the externally provided I/O CLOCK and lasts 8, 12, or 16 clock periods, depending on the selected output data length.

1. I/O cycle

During the I/O cycle, two operations take place simultaneously.

- a. An 8-bit data stream consisting of address and control information is provided to DATA INPUT. This data is shifted into the device on the rising edge of the first eight I/O CLOCKS. DATA INPUT is ignored after the first eight clocks during 12 or 16 clock I/O transfers.
- b. The data output, with a length of 8, 12, or 16 bits, is provided serially on DATA OUT. If \overline{CS} is held low, the first output data bit occurs on the rising edge of EOC. If \overline{CS} is negated between conversions, the first output data bit occurs on the falling edge of \overline{CS} . This data is the result of the previous conversion period, and after the first output data bit, each succeeding bit is clocked out on the falling edge of each succeeding I/O CLOCK.

2. Conversion cycle

The conversion cycle is transparent to the user, and it is controlled by an internal clock synchronized to I/O CLOCK. During the conversion period, the device performs a successive-approximation conversion on the analog input voltage. The EOC output goes low at the start of the conversion cycle and goes high when conversion is complete and the output data register is latched. A conversion cycle is started only after the I/O cycle is completed, which minimizes the influence of external digital noise on the accuracy of the conversion.

power up and initialization

After power up, \overline{CS} must be taken from high to low to begin an I/O cycle. EOC is initially high, and the input data register is set to all zeroes. The contents of the output data register are random, and the first conversion result should be ignored. To initialize during operation, \overline{CS} is taken high and returned low to begin the next I/O cycle. The first conversion after the device has returned from the power-down state may not read accurately due to internal device settling.

operational terminology

Current (N) I/O cycle	The entire I/O CLOCK sequence that transfers address and control data into the data register and clocks the digital result from the previous conversion from DATA OUT
Current (N) conversion cycle	The conversion cycle starts immediately after the current I/O cycle. The end of the current I/O cycle is the last clock falling edge in the I/O CLOCK sequence. The current conversion result is loaded into the output register when conversion is complete.
Current (N) conversion result	The current conversion result is serially shifted out on the next I/O cycle.
Previous (N-1) conversion cycle	The conversion cycle just prior to the current I/O cycle
Next (N+1) I/O cycle	The I/O period that follows the current conversion cycle

Example: In the 12-bit mode, the result of the current conversion cycle is a 12-bit serial-data stream clocked out during the next I/O cycle. The current I/O cycle must be exactly 12 bits long to maintain synchronization, even if this corrupts the output data from the previous conversion. The current conversion begins immediately after the twelfth falling edge of the current I/O cycle.

data input

The data input is internally connected to an 8-bit serial-input address and control register. The register defines the operation of the converter and the output data length. The host provides the data word with the MSB first. Each data bit is clocked in on the rising edge of the I/O CLOCK sequence (see Table 1 for the data register format).

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data input address bits

The four MSBs (D7 – D4) of the data register are used to address one of the 11 input channels, a reference-test voltage, or the power-down mode. The address bits affect the current conversion, which is the conversion that immediately follows the current I/O cycle. The reference voltage is nominally equal to $V_{ref+} - V_{ref-}$.

data output length

The next two bits (D3 and D2) of the data register select the output data length. The data-length selection is valid for the current I/O cycle (the cycle in which the data is read). The data-length selection, being valid for the current I/O cycle, allows device start up without losing I/O synchronization. A data length of 8, 12, or 16 bits can be selected. Since the converter has 12-bit resolution, a data length of 12 bits is suggested.

With D3 and D2 set to 00 or 10, the device is in the 12-bit data-length mode and the result of the current conversion is output as a 12-bit serial-data stream during the next I/O cycle. The current I/O cycle must be exactly 12 bits long for proper synchronization, even if this means corrupting the output data from a previous conversion. The current conversion is started immediately after the twelfth falling edge of the current I/O cycle.

With bits D3 and D2 set to 11, the 16-bit data-length mode is selected, which allows convenient communication with 16-bit serial interfaces. In the 16-bit mode, the result of the current conversion is output as a 16-bit serial-data stream during the next I/O cycle with the four LSBs always set to 0 (pad bits). The current I/O cycle must be exactly 16 bits long to maintain synchronization even if this means corrupting the output data from the previous conversion. The current conversion is immediately started after the 16th falling edge of the current I/O cycle.

With bits D3 and D2 set to 01, the 8-bit data-length mode is selected, which allows fast communication with 8-bit serial interfaces. In the 8-bit mode, the result of the current conversion is output as an 8-bit serial-data stream during the next I/O cycle. The current I/O cycle must be exactly 8 bits long to maintain synchronization, even if this means corrupting the output data from the previous conversion. The four LSBs of the conversion result are truncated and discarded. The current conversion is immediately started after the eighth falling edge of the current I/O cycle.

Since D3 and D2 take effect on the current I/O cycle when the data length is programmed, there can be a conflict with the previous cycle when the data-word length is changed from one cycle to the next. This may occur when the data format is selected to be least significant bit first, since at the time the data length change becomes effective (6 rising edges of I/O CLOCK), the previous conversion result has already started shifting out.

In actual operation, if different data lengths are required within an application and the data length is changed between two conversions, no more than one conversion result can be corrupted and only if it is shifted out in LSB first format.

sampling period

During the sampling period, one of the analog inputs is internally connected to the capacitor array of the converter to store the analog input signal. The converter starts sampling the selected input immediately after the four address bits have been clocked into the input data register. Sampling starts on the fourth falling edge of I/O CLOCK. The converter remains in the sampling mode until the eighth, twelfth, or sixteenth falling edge of the I/O CLOCK depending on the data-length selection. After the EOC delay time from the last I/O CLOCK falling edge, the EOC output goes low indicating that the sampling period is over and the conversion period has begun. After EOC goes low, the analog input can be changed without affecting the conversion result. Since the delay from the falling edge of the last I/O CLOCK to EOC low is fixed, time-varying analog input signals can be digitized at a fixed rate without introducing systematic harmonic distortion or noise due to timing uncertainty.

After the 8-bit data stream has been clocked in, DATA INPUT should be held at a fixed digital level until EOC goes high (indicating the conversion is complete) to maximize the sampling accuracy and minimize the influence of external digital noise.

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data register, LSB first

D1 in the input data register (LSB first) is used to control the direction of the output binary data transfer. When D1 is set to 0, the conversion result is shifted out MSB first. When set to 1, the data is shifted out LSB first. Selection of MSB first or LSB first always affects the next I/O cycle and not the current I/O cycle. When changing from one data direction to another, the current I/O cycle is never disrupted.

data register, bipolar format

D0 in the input data register is used to control the binary data format used to represent the conversion result. When D0 is set to 0, the conversion result is represented as unipolar (unsigned binary) data. Nominally, the conversion result of an input voltage equal to V_{ref-} is a code of all zeros (000 . . . 0), the conversion result of an input voltage equal to V_{ref+} is a code of all ones (111 . . . 1), and the conversion result of $(V_{ref+} + V_{ref-})/2$ is a code of a one followed by zeros (100 . . . 0).

When D0 is set to 1, the conversion result is represented as bipolar (BIP) (signed binary) data. Nominally, conversion of an input voltage equal to V_{ref-} is a code of a 1 followed by zeros (100 . . . 0), conversion of an input voltage equal to V_{ref+} is a code of a 0 followed by all ones (011 . . . 1), and the conversion of $(V_{ref+} + V_{ref-})/2$ is a code of all zeros (000 . . . 0). The MSB is interpreted as the sign bit. The bipolar data format is related to the unipolar format in that the MSBs are always each other's complement.

Selection of the unipolar or bipolar format always affects the current conversion cycle, and the result is output during the next I/O cycle. When changing between unipolar and bipolar formats, the data output during the current I/O cycle is not affected.

EOC output

The EOC signal indicates the beginning and the end of conversion. In the reset state, EOC is always high. During the sampling period (beginning after the fourth falling edge of the I/O CLOCK sequence), EOC remains high until the internal sampling switch of the converter is safely opened. The opening of the sampling switch occurs after the eighth, twelfth, or sixteenth I/O CLOCK falling edge, depending on the data-length selection in the input data register. After the EOC signal goes low, the analog input signal can be changed without affecting the conversion result.

The EOC signal goes high again after the conversion is completed and the conversion result is latched into the output data register. The rising edge of EOC returns the converter to a reset state and a new I/O cycle begins. On the rising edge of EOC, the first bit of the current conversion result is on DATA OUT if \overline{CS} is low. If \overline{CS} is negated between conversions, the first bit of the current conversion result occurs at DATA OUT on the falling edge of \overline{CS} .

data format and pad bits

D3 and D2 of the input data register determine the number of significant bits in the digital output that represent the conversion result. The LSB-first bit determines the direction of the data transfer while the BIP bit determines the arithmetic conversion. The numerical data is always justified toward the MSB in any output format.

The internal conversion result is always 12 bits long. When an 8-bit data transfer is selected, the four LSBs of the internal result are discarded to provide a faster one-byte transfer. When a 12-bit transfer is used, all bits are transferred. When a 16-bit transfer is used, four LSB pad bits are always appended to the internal conversion result. In the LSB-first mode, four leading zeros are output. In the MSB-first mode, the last four bits output are zeros.

When \overline{CS} is held low continuously, the first data bit of the just completed conversion occurs on DATA OUT on the rising edge of EOC. When a new conversion is started after the last falling edge of I/O CLOCK, EOC goes low and the serial output is forced to a logic zero until EOC goes high again.

When \overline{CS} is negated between conversions, the first data bit occurs on DATA OUT on the falling edge of \overline{CS} . On each subsequent falling edge of I/O CLOCK after the first data bit appears, the data is changed to the next bit in the serial conversion result until the required number of bits has been output.

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chip-select Input (\overline{CS})

The chip-select input (\overline{CS}) enables and disables the device. During normal operation, \overline{CS} should be low. Although the use of \overline{CS} is not necessary to synchronize a data transfer, it can be brought high between conversions to coordinate the data transfer of several devices sharing the same bus.

When \overline{CS} is brought high, the serial-data output is immediately brought to the high-impedance state, releasing its output data line to other devices that may share it. After an internally generated debounce time, the I/O CLOCK is inhibited, thus preventing any further change in the internal state.

When \overline{CS} is subsequently brought low again, the device is reset. \overline{CS} must be held low for an internal debounce time before the reset operation takes effect. After \overline{CS} is debounced low, I/O CLOCK must remain inactive (low) for a minimum time before a new I/O cycle can start.

\overline{CS} can be used to interrupt any ongoing data transfer or any ongoing conversion. If \overline{CS} is debounced low long enough before the end of the current conversion cycle, the previous conversion result is saved in the internal output buffer and shifted out during the next I/O cycle.

power-down features

When a binary address of 1110 is clocked into the input data register during the first four I/O CLOCK cycles, the power-down mode is selected. Power down is activated on the falling edge of the fourth I/O CLOCK pulse.

During power down, all internal circuitry is put in a low-current standby mode. No conversions are performed, and the internal output buffer keeps the previous conversion cycle data results, provided that all digital inputs are held above $V_{CC} - 0.5\text{ V}$ or below 0.5 V. The I/O logic remains active so the current I/O cycle must be completed even when the power-down mode is selected. Upon power-on reset and before the first I/O cycle, the converter normally begins in the power-down mode. The device remains in the power-down mode until a valid (other than 1110) input address is clocked in. Upon completion of that I/O cycle, a normal conversion is performed with the results being shifted out during the next I/O cycle.

analog input, test, and power-down mode

The 11 analog inputs, three internal voltages, and power-down mode are selected by the input multiplexer according to the input addresses shown in Tables 2, 3, and 4. The input multiplexer is a break-before-make type to reduce input-to-input noise rejection resulting from channel switching. Sampling of the analog input starts on the falling edge of the fourth I/O CLOCK and continues for the remaining I/O CLOCK pulses. The sample is held on the falling edge of the last I/O CLOCK pulse. The three internal test inputs are applied to the multiplexer, sampled, and converted in the same manner as the external analog inputs. The first conversion after the device has returned from the power-down state may not read accurately due to internal device settling.

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detailed description (continued)

Table 1. Input-Register Format

FUNCTION SELECT	INPUT DATA BYTE							
	ADDRESS BITS				L1	L0	LSBF	BIP
	D7 (MSB)	D6	D5	D4	D3	D2	D1	D0 (LSB)
Select input channel								
AIN0 _____	0	0	0	0				
AIN1 _____	0	0	0	1				
AIN2 _____	0	0	1	0				
AIN3 _____	0	0	1	1				
AIN4 _____	0	1	0	0				
AIN5 _____	0	1	0	1				
AIN6 _____	0	1	1	0				
AIN7 _____	0	1	1	1				
AIN8 _____	1	0	0	0				
AIN9 _____	1	0	0	1				
AIN10 _____	1	0	1	0				
Select test voltage								
$(V_{ref+} - V_{ref-})/2$ _____	1	0	1	1				
V_{ref-} _____	1	1	0	0				
V_{ref+} _____	1	1	0	1				
Software power down _____	1	1	1	0				
Output data length								
8 bits _____					0	1		
12 bits _____					X	0		
16 bits _____					1	1		
Output data format								
MSB first _____							0	
LSB first _____							1	
Unipolar (binary) _____								0
Bipolar (2s complement) _____								1

Table 2. Analog-Channel-Select Address

ANALOG INPUT SELECTED	VALUE SHIFTED INTO DATA INPUT	
	BINARY	HEX
AIN0	0000	0
AIN1	0001	1
AIN2	0010	2
AIN3	0011	3
AIN4	0100	4
AIN5	0101	5
AIN6	0110	6
AIN7	0111	7
AIN8	1000	8
AIN9	1001	9
AIN10	1010	A

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detailed description (continued)

Table 3. Test-Mode-Select Address

INTERNAL SELF-TEST VOLTAGE SELECTED†	VALUE SHIFTED INTO DATA INPUT		UNIPOLAR OUTPUT RESULT (HEX)‡
	BINARY	HEX	
$\frac{V_{ref+} - V_{ref-}}{2}$	1011	B	200
V_{ref-}	1100	C	000
V_{ref+}	1101	D	3FF

† V_{ref+} is the voltage applied to REF+, and V_{ref-} is the voltage applied to REF-.

‡ The output results shown are the ideal values and may vary with the reference stability and with internal offsets.

Table 4. Power-Down-Select Address

INPUT COMMAND	VALUE SHIFTED INTO DATA INPUT		RESULT
	BINARY	HEX	
Power down	1110	E	$I_{CC} \leq 25 \mu A$

converter and analog input

The CMOS threshold detector in the successive-approximation conversion system determines each bit by examining the charge on a series of binary-weighted capacitors (see Figure 1). In the first phase of the conversion process, the analog input is sampled by closing the S_C switch and all S_T switches simultaneously. This action charges all the capacitors to the input voltage.

In the next phase of the conversion process, all S_T and S_C switches are opened and the threshold detector begins identifying bits by identifying the charge (voltage) on each capacitor relative to the reference (REF-) voltage. In the switching sequence, 12 capacitors are examined separately until all 12 bits are identified and the charge-convert sequence is repeated. In the first step of the conversion phase, the threshold detector looks at the first capacitor (weight = 4096). Node 4096 of this capacitor is switched to the REF+ voltage, and the equivalent nodes of all the other capacitors on the ladder are switched to REF-. If the voltage at the summing node is greater than the trip point of the threshold detector (approximately one-half V_{CC}), a bit 0 is placed in the output register and the 4096-weight capacitor is switched to REF-. If the voltage at the summing node is less than the trip point of the threshold detector, a bit 1 is placed in the register and this 4096-weight capacitor remains connected to REF+ through the remainder of the successive-approximation process. The process is repeated for the 2048-weight capacitor, the 1024-weight capacitor, and so forth, down the line until all bits are determined. With each step of the successive-approximation process, the initial charge is redistributed among the capacitors. The conversion process relies on charge redistribution to determine the bits from MSB to LSB.

reference voltage inputs

There are two reference voltage inputs on the device: REF+ and REF-. The voltage values on these terminals establish the upper and lower limits of the analog input to produce a full-scale and zero-scale reading respectively. These voltages and the analog input should not exceed the positive supply or be lower than ground consistent with the specified absolute maximum ratings. The digital output is at full scale when the input signal is equal to or higher than REF+ terminal voltage and at zero when the input signal is equal to or lower than REF- terminal voltage.

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detailed description (continued)

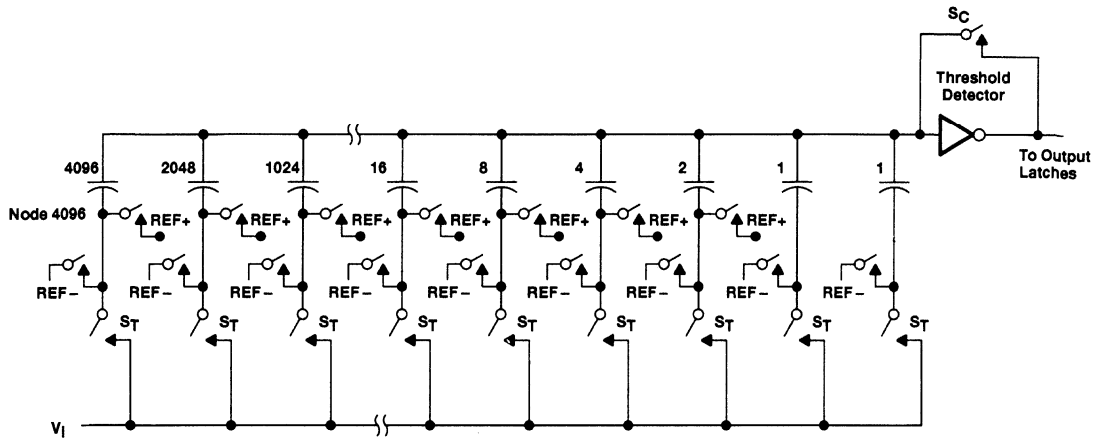


Figure 1. Simplified Model of the Successive-Approximation System

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC} (see Note 1)	–0.5 V to 6.5 V
Input voltage range, V_I (any input)	–0.3 V to $V_{CC} + 0.3$ V
Output voltage range, V_O	–0.3 V to $V_{CC} + 0.3$ V
Positive reference voltage, V_{ref+}	$V_{CC} + 0.1$ V
Negative reference voltage, V_{ref-}	–0.1 V
Peak input current, I_I (any input)	±20 mA
Peak total input current (all inputs)	±30 mA
Operating free-air temperature range, T_A : TLV2543C	0°C to 70°C
TLV2543I	–40°C to 85°C
Storage temperature range, T_{stg}	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from the case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the GND terminal with REF– and GND wired together (unless otherwise noted).

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}	3	3.3	3.6	V
Positive reference voltage, V_{ref+} (see Note 2)	V_{CC}			V
Negative reference voltage, V_{ref-} (see Note 2)	0			V
Differential reference voltage, $V_{ref+} - V_{ref-}$ (see Note 2)	2.5	V_{CC}	$V_{CC} + 0.1$	V
Analog input voltage (see Note 2)	0			V_{CC}
High-level control input voltage, V_{IH}	$V_{CC} = 3$ V to 3.6 V			2
Low-level control input voltage, V_{IL}	$V_{CC} = 3$ V to 3.6 V			0.8
Clock frequency at I/O CLOCK	0	3		MHz
Setup time, address bits at DATA INPUT before I/O CLOCK↑, $t_{su(A)}$ (see Figure 5)	100			ns
Hold time, address bits after I/O CLOCK↑, $t_h(A)$ (see Figure 5)	0			ns
Hold time, \overline{CS} low after last I/O CLOCK↓, $t_h(CS)$ (see Figure 6)	0			ns
Setup time, \overline{CS} low before clocking in first address bit, $t_{su}(CS)$ (see Note 3 and Figure 6)	1.425			μs
Pulse duration, I/O CLOCK high, $t_{wH}(I/O)$	190			ns
Pulse duration, I/O CLOCK low, $t_{wL}(I/O)$	190			ns
Transition time, I/O CLOCK, $t_t(I/O)$ (see Note 4 and Figure 7)			1	μs
Transition time, DATA INPUT and \overline{CS} , $t_t(CS)$			10	μs
Operating free-air temperature, T_A	TLV2543C	0	70	°C
	TLV2543I	–40	85	

NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (111111111111), while input voltages less than that applied to REF– convert as all zeros (000000000000).

3. To minimize errors caused by noise at the \overline{CS} input, the internal circuitry waits for a setup time after \overline{CS} ↓ before responding to control input signals. No attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

4. This is the time required for the clock input signal to fall from V_{IHmin} to V_{ILmax} or to rise from V_{ILmax} to V_{IHmin} . In the vicinity of normal room temperature, the devices function with input clock transition time as slow as 1 μs for remote data acquisition applications where the sensor and the A/D converter are placed several feet away from the controlling microprocessor.

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electrical characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 3\text{ V to }3.6\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	V _{CC} = 3 V, I _{OH} = -0.3 mA	2.4			V
		V _{CC} = 3 V to 3.6 V, I _{OH} = -20 μA	V _{CC} - 0.1			
V _{OL}	Low-level output voltage	V _{CC} = 3 V, I _{OL} = 0.8 mA			0.4	V
		V _{CC} = 3 V to 3.6 V, I _{OL} = 20 μA			0.1	
I _{OZ}	Off-state (high-impedance-state) output current	V _O = V _{CC} , \overline{CS} at V _{CC}		1	2.5	μA
		V _O = 0, \overline{CS} at V _{CC}		1	-2.5	
I _{IH}	High-level input current	V _I = V _{CC}		1	2.5	μA
I _{IL}	Low-level input current	V _I = 0		1	-2.5	μA
I _{CC}	Operating supply current	\overline{CS} at 0 V		1	2.5	mA
I _{CC(PD)}	Power-down current	For all digital inputs, 0 ≤ V _I ≤ 0.5 V or V _I ≥ V _{CC} - 0.5 V		4	25	μA
Selected channel leakage current		Selected channel at V _{CC} , Unselected channel at 0 V			1	μA
		Selected channel at 0 V, Unselected channel at V _{CC}			-1	
Maximum static analog reference current into REF ₊		V _{ref+} = V _{CC} , V _{ref-} = GND		1	2.5	μA
C _i	Input capacitance	Analog inputs		30	60	pF
		Control inputs		5	15	

† All typical values are at V_{CC} = 5 V, T_A = 25°C.

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operating characteristics over recommended operating free-air temperature range,
 $V_{CC} = V_{ref+} = 3\text{ V to }3.6\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
E_L	Linearity error (see Note 6)	See Figure 2			±1	LSB
E_D	Differential linearity error	See Figure 2			±1	LSB
E_O	Offset error (see Note 7)	See Note 2 and Figure 2			±1.5	LSB
E_G	Gain error (see Note 7)	See Note 2 and Figure 2			±1	LSB
E_T	Total unadjusted error (see Note 8)				±1.75	LSB
Self-test output code (see Table 3 and Note 9)		DATA INPUT = 1011		2048		
		DATA INPUT = 1100		0		
		DATA INPUT = 1101		4095		
t_{conv}	Conversion time	See Figures 10–15		8		µs
t_c	Total cycle time (access, sample, and conversion)	See Figures 10–15 and Note 10			10 + total I/O CLOCK periods + $t_d(I/O-EOC)$	µs
t_{acq}	Channel acquisition time (sample)	See Figures 10–15 and Note 10	4		12	I/O CLOCK periods
t_v	Valid time, DATA OUT remains valid after I/O CLOCK↓	See Figure 7	10			ns
$t_d(I/O-DATA)$	Delay time, I/O CLOCK↓ to DATA OUT valid	See Figure 7			150	ns
$t_d(I/O-EOC)$	Delay time, last I/O CLOCK↓ to EOC↓	See Figure 8		1.5	2.2	µs
$t_d(EOC-DATA)$	Delay time, EOC↑ to DATA OUT (MSB/LSB)	See Figure 9			100	ns
t_{PZH}, t_{PZL}	Enable time, \overline{CS} ↓ to DATA OUT (MSB/LSB driven)	See Figure 4		0.7	1.3	µs
t_{PHZ}, t_{PLZ}	Disable time, \overline{CS} ↑ to DATA OUT (high impedance)	See Figure 4		70	150	ns
$t_r(EOC)$	Rise time, EOC	See Figure 9		15	50	ns
$t_f(EOC)$	Fall time, EOC	See Figure 8		15	50	ns
$t_r(\text{bus})$	Rise time, data bus	See Figure 7		15	50	ns
$t_f(\text{bus})$	Fall time, data bus	See Figure 7		15	50	ns
$t_d(I/O-CS)$	Delay time, last I/O CLOCK↓ to \overline{CS} ↓ to abort conversion (see Note 11)				5	µs

† All typical values are at $T_A = 25^\circ\text{C}$.

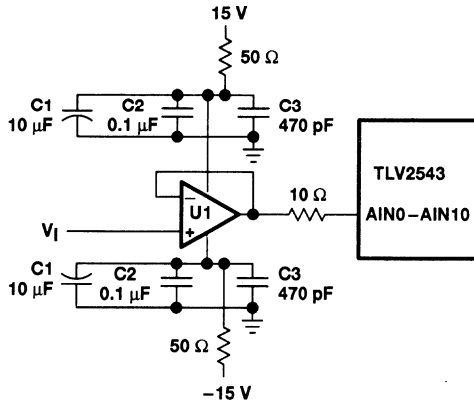
- NOTES: 2. Analog input voltages greater than that applied to REF+ convert as all ones (1111111111), while input voltages less than that applied to REF- convert as all zeros (000000000000).
6. Linearity error is the maximum deviation from the best straight line through the A/D transfer characteristics.
7. Gain error is the difference between the actual midstep value and the nominal midstep value in the transfer diagram at the specified gain point after the offset error has been adjusted to zero. Offset error is the difference between the actual midstep value and the nominal midstep value at the offset point.
8. Total unadjusted error comprises linearity, zero-scale, and full-scale errors.
9. Both the input address and the output codes are expressed in positive logic.
10. I/O CLOCK period = 1/(I/O CLOCK frequency) (see Figure 7).
11. Any transitions of \overline{CS} are recognized as valid only if the level is maintained for a setup time. \overline{CS} must be taken low at $\leq 5\text{ }\mu\text{s}$ of the tenth I/O CLOCK falling edge to assure a conversion is aborted. Between $5\text{ }\mu\text{s}$ and $10\text{ }\mu\text{s}$, the result is uncertain as to whether the conversion is aborted or the conversion results are valid.

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LOCATION	DESCRIPTION	PART NUMBER
U1	OP27	—
C1	10- μ F 35-V tantalum capacitor	—
C2	0.1- μ F ceramic NPO SMD capacitor	AVX 12105C104KA105 or equivalent
C3	470-pF porcelain high-Q SMD capacitor	Johanson 201S420471JG4L or equivalent

Figure 2. Analog Input Buffer to Analog Inputs AIN0–AIN10

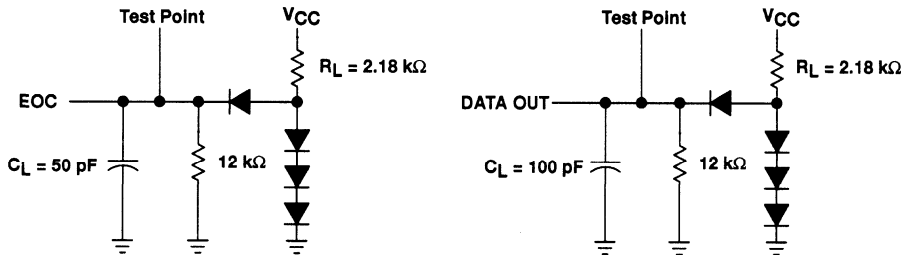


Figure 3. Load Circuits

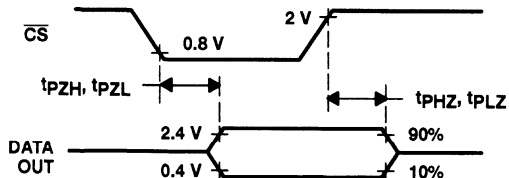


Figure 4. DATA OUT to Hi-Z Voltage Waveforms

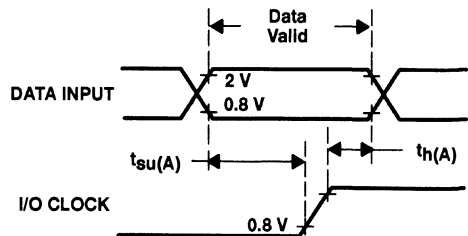


Figure 5. DATA INPUT and I/O CLOCK Voltage Waveforms

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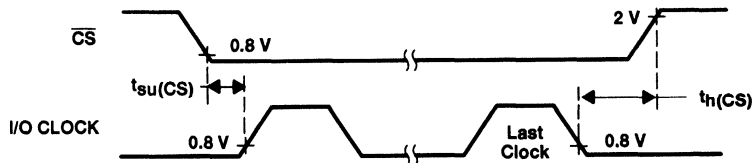


Figure 6. \overline{CS} and I/O CLOCK Voltage Waveforms†

† To ensure full conversion accuracy, it is recommended that no input signal change occurs while a conversion is ongoing.

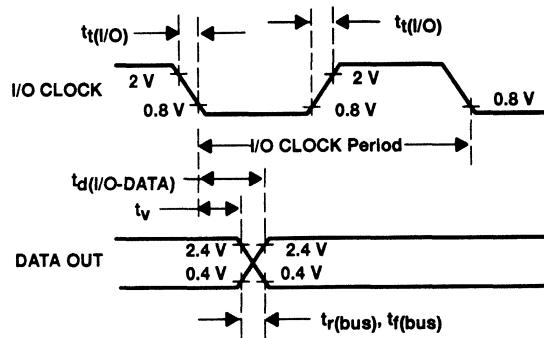


Figure 7. I/O CLOCK and DATA OUT Voltage Waveforms

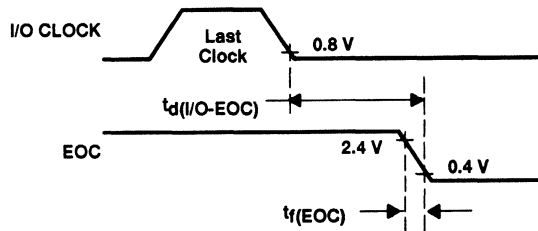


Figure 8. I/O CLOCK and EOC Voltage Waveforms

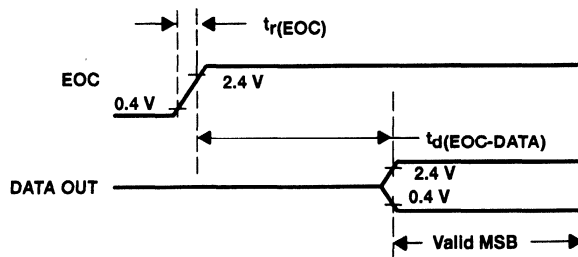


Figure 9. EOC and DATA OUT Voltage Waveforms

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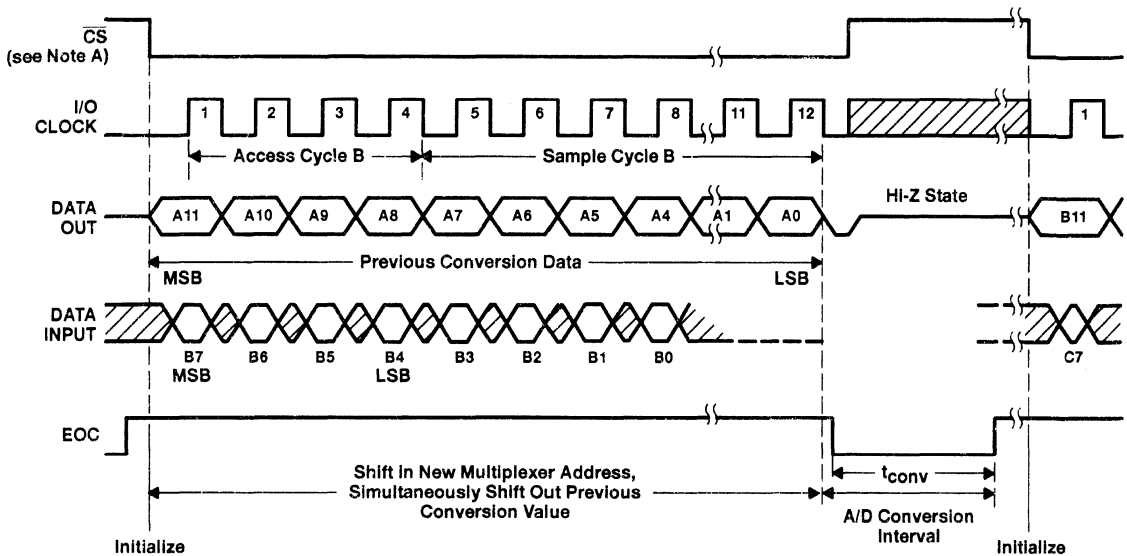


Figure 10. Timing for 12-Clock Transfer Using \overline{CS} With MSB First

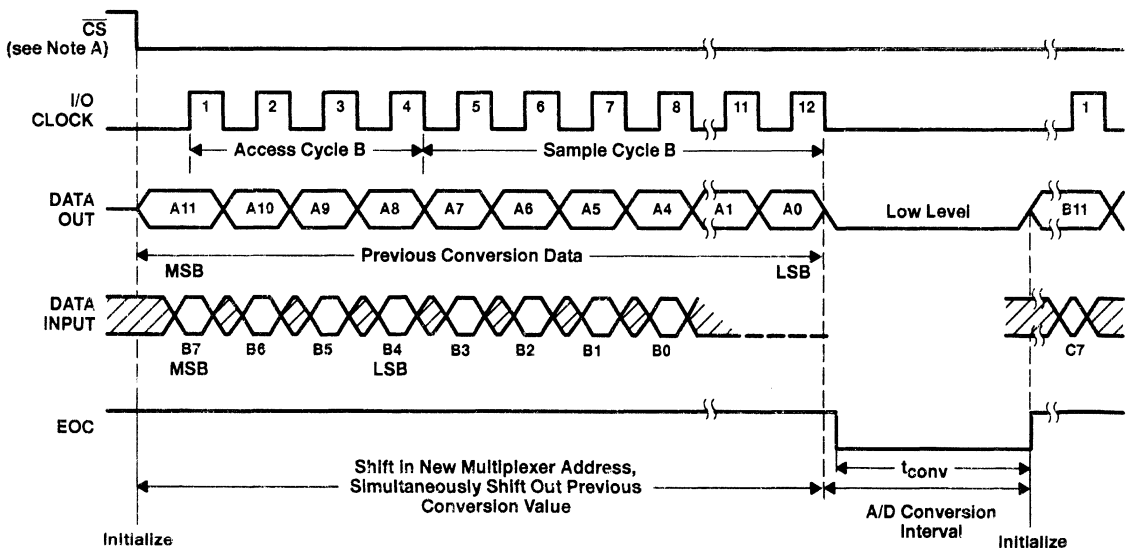


Figure 11. Timing for 12-Clock Transfer Not Using \overline{CS} With MSB First

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

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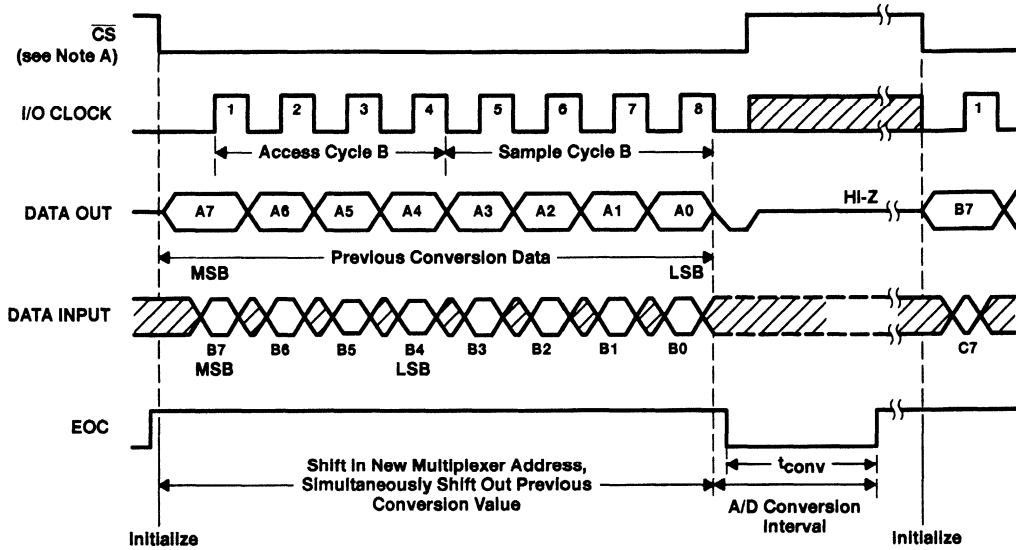


Figure 12. Timing for 8-Clock Transfer Using \overline{CS} With MSB First

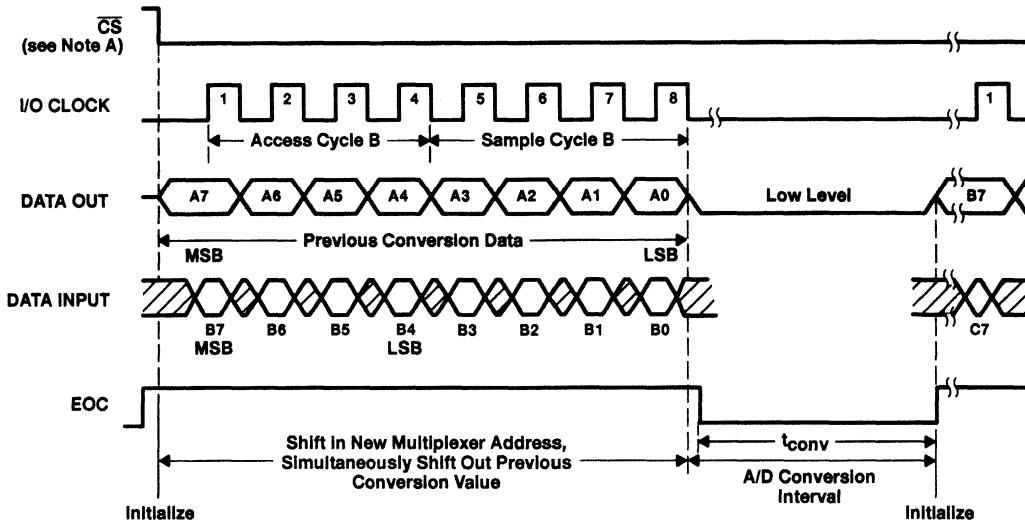


Figure 13. Timing for 8-Clock Transfer Not Using \overline{CS} With MSB First

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

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PARAMETER MEASUREMENT INFORMATION

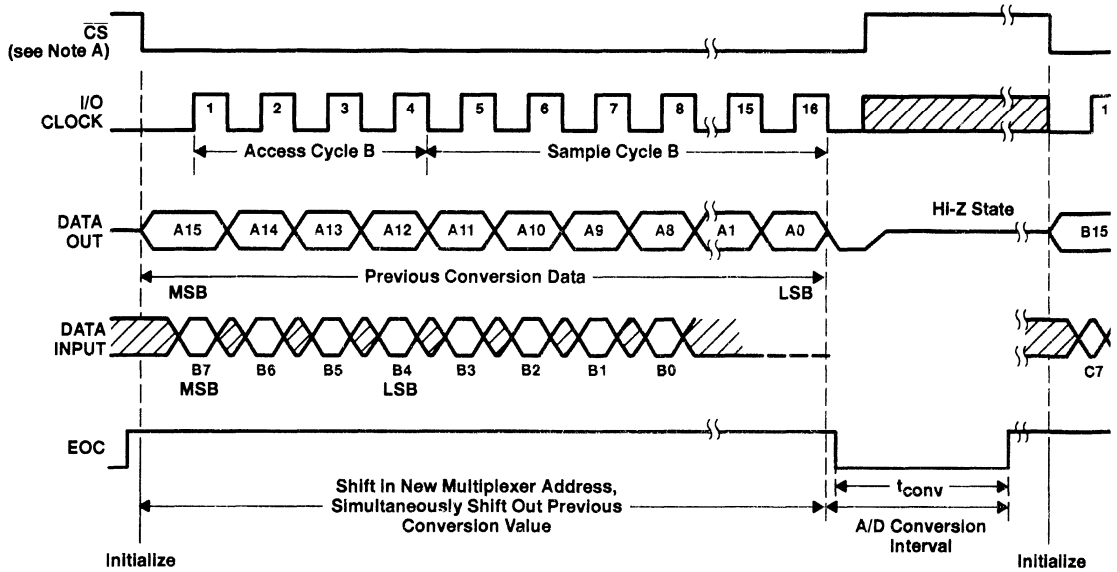


Figure 14. Timing for 16-Clock Transfer Using \overline{CS} With MSB First

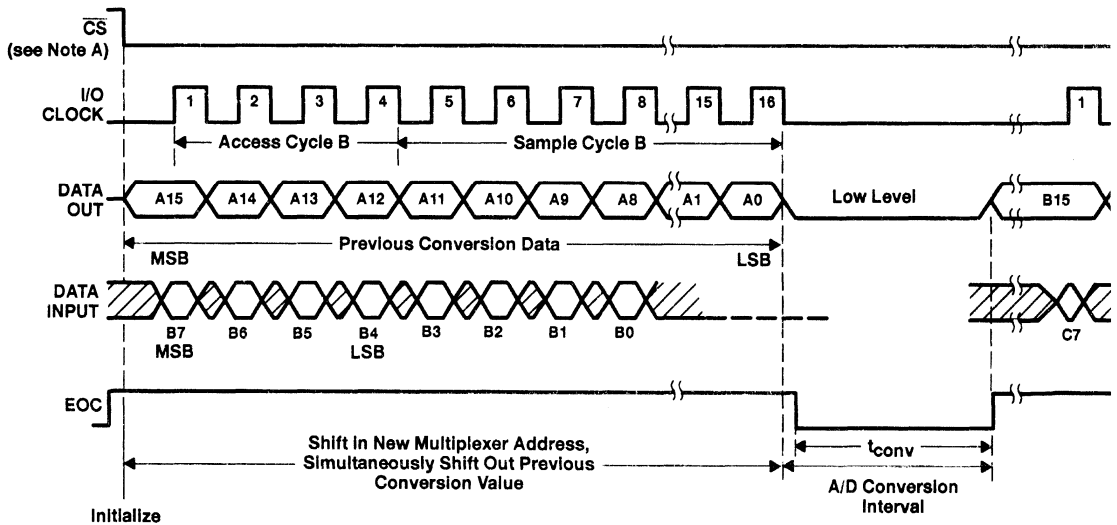
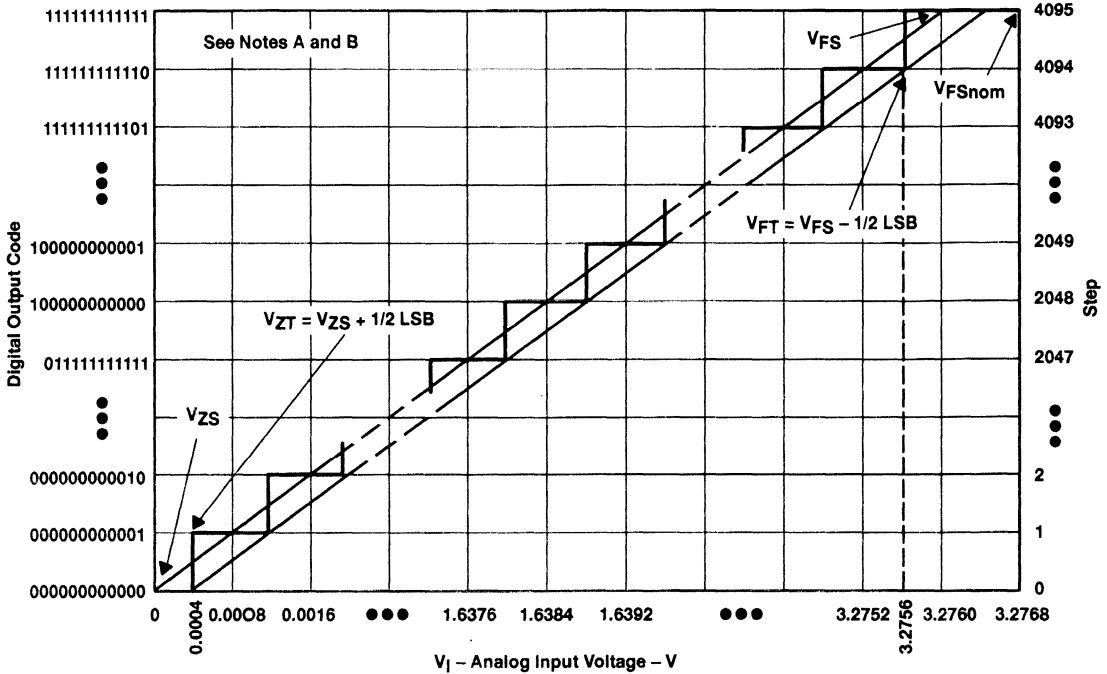


Figure 15. Timing for 16-Clock Transfer Not Using \overline{CS} With MSB First

NOTE A: To minimize errors caused by noise at \overline{CS} , the internal circuitry waits for a setup time after $\overline{CS}\downarrow$ before responding to control input signals. Therefore, no attempt should be made to clock in an address until the minimum \overline{CS} setup time has elapsed.

PRODUCT PREVIEW

APPLICATION INFORMATION



- NOTES: A. This curve is based on the assumption that V_{ref+} and V_{ref-} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 0.0006 V and the transition to full scale (V_{FT}) is 4.9134 V. 1 LSB = 1.2 mV.
 B. The full-scale value (V_{FS}) is the step whose nominal midstep value has the highest absolute value. The zero-scale value (V_{ZS}) is the step whose nominal midstep value equals zero.

Figure 16. Ideal Conversion Characteristics

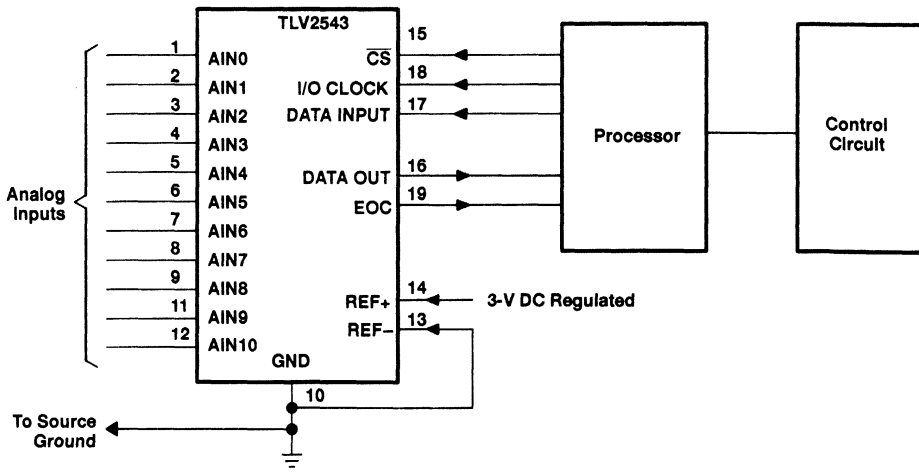


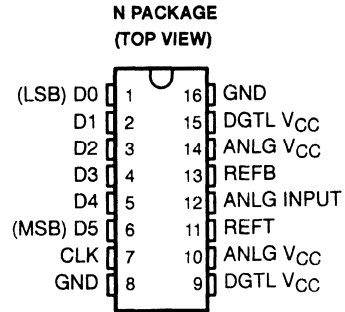
Figure 17. Serial Interface

PRODUCT PREVIEW

TL5501 6-BIT ANALOG-TO-DIGITAL CONVERTER

SLAS026 – D3163, OCTOBER 1989 – REVISED APRIL 1990

- 6-Bit Resolution
- Linearity Error . . . $\pm 0.8\%$
- Maximum Conversion Rate . . . 30 MHz Typ
- Analog Input Voltage Range
V_{CC} to V_{CC} - 2 V
- Analog Input Dynamic Range . . . 1 V
- TTL Digital I/O Level
- Low Power Consumption
200 mW Typ
- 5-V Single-Supply Operation
- Interchangeable With Fujitsu MB40576

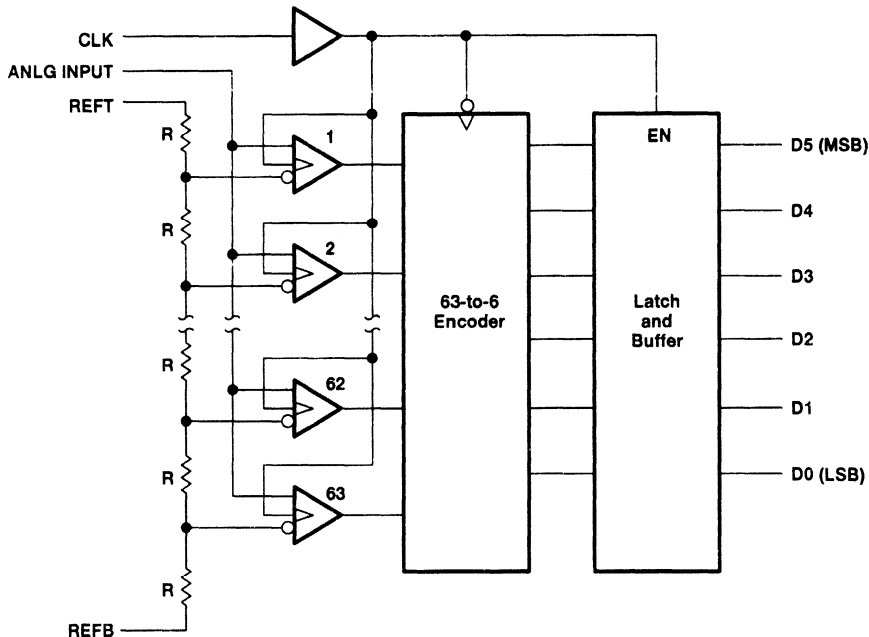


description

The TL5501 is a low-power ultra-high-speed video-band analog-to-digital converter that uses the Advanced Low-Power Schottky (ALS) process. It utilizes the full-parallel comparison (flash method) for high-speed conversion. It converts wide-band analog signals (such as a video signal) to a digital signal at a sampling rate of dc to 30 MHz. Because of this high-speed capability, the TL5501 is suitable for digital video applications such as digital TV, video processing with a computer, or radar signal processing.

The TL5501 is characterized for operation from 0°C to 70°C.

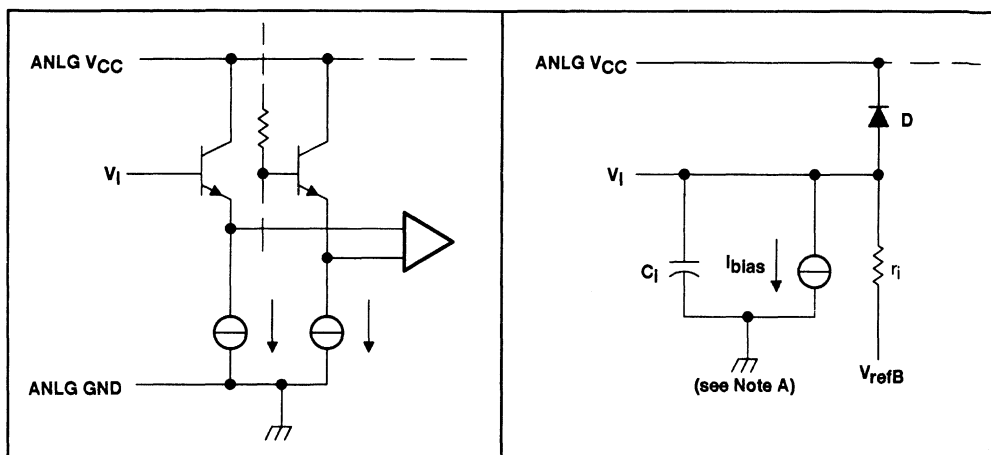
functional block diagram



TL5501 6-BIT ANALOG-TO-DIGITAL CONVERTER

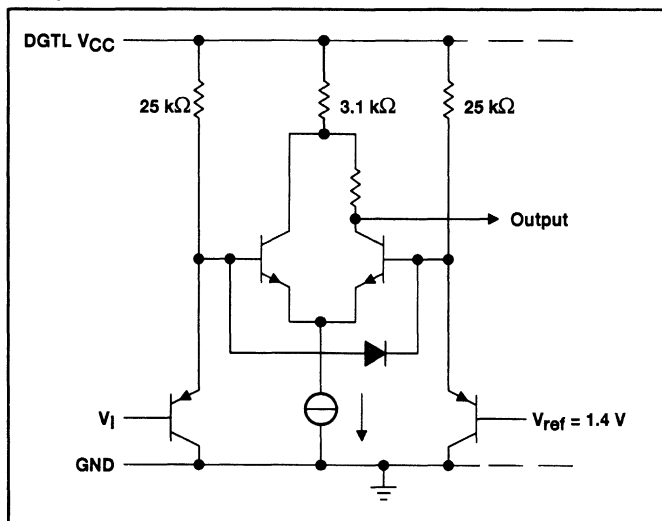
SLAS026 – D3163, OCTOBER 1989 – REVISED APRIL 1990

equivalents of analog input circuit



NOTE A: C_i – nonlinear emitter-follower junction capacitance
 r_i – linear resistance model for input current transition caused by comparator switching. $V_I < V_{refB}$: Infinite; CLK high: infinite.
 V_{refB} – voltage at REFB terminal
 I_{bias} – constant input bias current
 D – base-collector junction diode of emitter-follower transistor

equivalent of digital input circuit



TL5501 6-BIT ANALOG-TO-DIGITAL CONVERTER

SLAS026 – D3163, OCTOBER 1989 – REVISED APRIL 1990

FUNCTION TABLE

STEP	ANALOG INPUT VOLTAGE	DIGITAL OUTPUT CODE					
0	3.992 V	L	L	L	L	L	L
1	4.008 V	L	L	L	L	L	H
31	4.488 V	L	H	H	H	H	H
32	4.508 V	H	L	L	L	L	L
33	4.520 V	H	L	L	L	L	H
62	4.984 V	H	H	H	H	H	L
63	5.000 V	H	H	H	H	H	H

† These values are based on the assumption that V_{refB} and V_{refT} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 4.000 V and the transition to full scale (V_{FT}) is 4.992 V. 1 LSB = 16 mV.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, ANLG V_{CC} (see Note 1)	–0.5 V to 7 V
Supply voltage range, DGTL V_{CC}	–0.5 V to 7 V
Input voltage range at digital input, V_I	–0.5 V to 7 V
Input voltage range at analog input, V_I	–0.5 V to ANLG $V_{CC} + 0.5$ V
Analog reference voltage range, V_{ref}	–0.5 V to ANLG $V_{CC} + 0.5$ V
Storage temperature range	–55°C to 150°C
Operating free-air temperature range	0°C to 70°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

NOTE 1: All voltage values are with respect to the network ground terminal.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, ANLG V_{CC}	4.75	5	5.25	V
Supply voltage, DGTL V_{CC}	4.75	5	5.25	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
Input voltage at analog input, V_I (see Note 2)	4		5	V
Analog reference voltage (top side), V_{refT} (see Note 2)	4	5	5.1	V
Analog reference voltage (bottom side), V_{refB} (see Note 2)	3	4	4.1	V
High-level output current, I_{OH}	–400			μA
Low-level output current, I_{OL}			4	mA
Clock pulse duration, high-level or low-level, t_w	25			ns
Operating free-air temperature, T_A	0		70	°C

NOTE 2: $V_{refB} < V_I < V_{refT}$. $V_{refT} - V_{refB} = 1 \text{ V} \pm 0.1 \text{ V}$.

TL5501 6-BIT ANALOG-TO-DIGITAL CONVERTER

SLAS026 – D3163, OCTOBER 1989 – REVISED APRIL 1990

electrical characteristics over operating supply voltage range, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

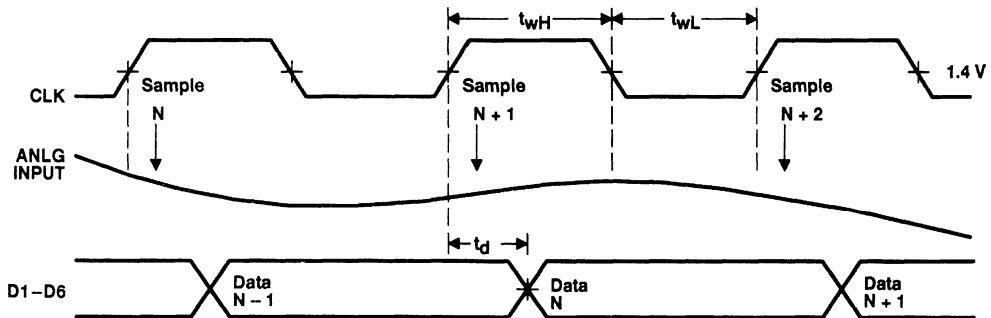
PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_I Analog input current	$V_I = 5\text{ V}$			75	μA
	$V_I = 4\text{ V}$			73	
I_{IH} Digital high-level input current	$V_I = 2.7\text{ V}$		0	20	μA
I_{IL} Digital low-level input current	$V_I = 0.4\text{ V}$	-400	-40		μA
I_I Digital input current	$V_I = 7\text{ V}$			100	μA
I_{refB} Reference current	$V_{IrefB} = 4\text{ V}$		-4	-7.2	mA
I_{refT} Reference current	$V_{IrefB} = 5\text{ V}$		4	7.2	mA
V_{OH} High-level output voltage	$I_{OH} = -400\ \mu\text{A}$		2.7		V
V_{OL} Low-level output voltage	$I_{OL} = 1.6\text{ mA}$			0.4	V
r_i Analog input resistance		100			k Ω
$1C_i$ Analog input capacitance			35	65	pF
I_{CC} Supply current			40	60	mA

operating characteristics over operating supply voltage range, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
E_L Linearity error				± 0.8	%FSR
f_{max} Maximum conversion rate		20	30		MHz
t_d Digital output delay time	See Figure 3		15	30	ns

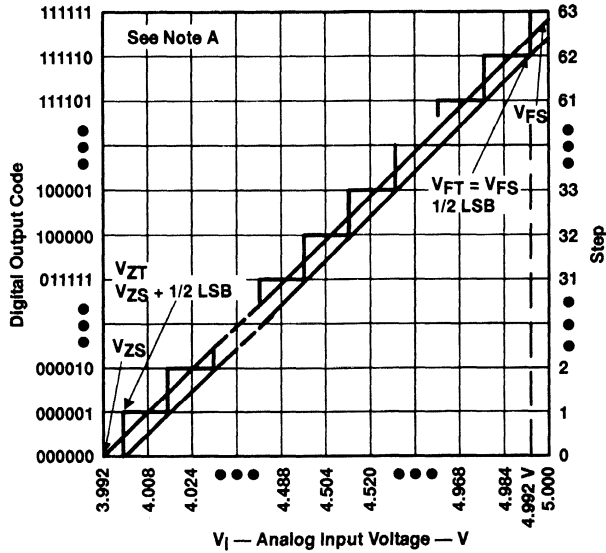
† All typical values are at $V_{CC} = 5\text{ V}$, $V_{ref} = 4\text{ V}$, $T_A = 25^\circ\text{C}$.

timing diagram



TYPICAL CHARACTERISTICS

IDEAL CONVERSION CHARACTERISTICS



NOTE A: This curve is based on the assumption that V_{refB} and V_{refT} have been adjusted so that the voltage at the transition from digital 0 to 1 (V_{ZT}) is 4.000 V and the transition to full scale (V_{FT}) is 4.992 V. 1 LSB = 16 mV.

Figure 1

END-POINT LINEARITY ERROR

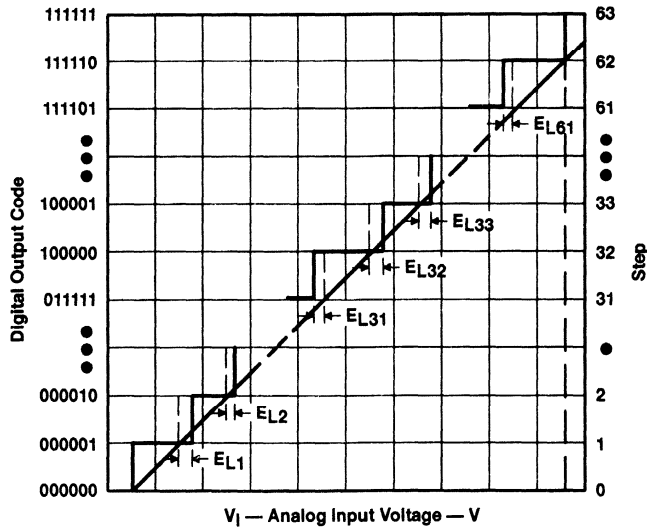


Figure 2

TL5501 6-BIT ANALOG-TO-DIGITAL CONVERTER

SLAS026 - D3163, OCTOBER 1989 - REVISED APRIL 1990

PARAMETER MEASUREMENT INFORMATION

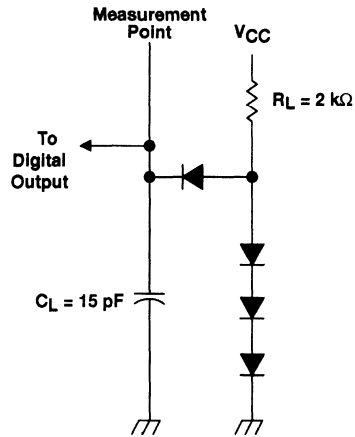


Figure 3. Load Circuit

General Information	1
General Purpose ADCs	2
General Purpose DACs	3
DSP Analog Interface and Conversion	4
Special Functions	5
Video Interface Palettes	6
Data Manuals	7
Application Reports	8
Mechanical Data	9
Appendix	A

3 General Purpose DACs

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

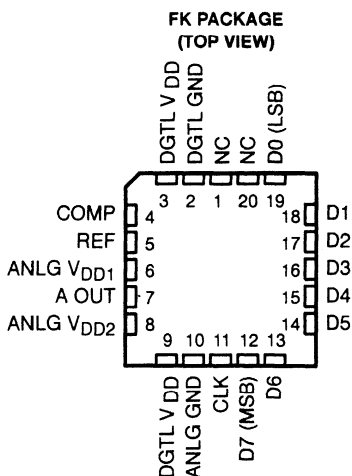
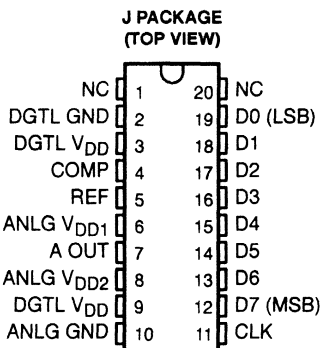
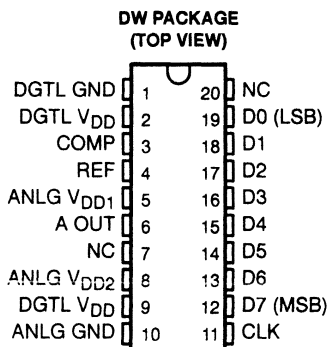
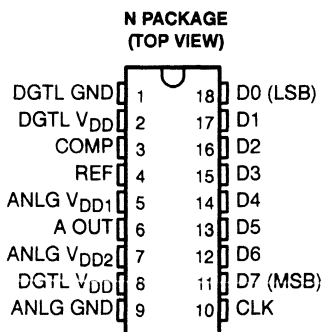
SLAS023C – FEBRUARY 1989 – REVISED MAY 1995

- 8-Bit Resolution
- $\pm 0.2\%$ Linearity
- Maximum Conversion Rate
30 MHz Typ
20 MHz Min
- Analog Output Voltage Range
 V_{DD} to $V_{DD} - 1\text{ V}$
- TTL Digital Input Voltage
- 5-V Single Power-Supply Operation
- Low Power Consumption 80 mW Typ
- Interchangeable With Fujitsu MB40778

description

The TLC5602x devices are low-power, ultra-high-speed video, digital-to-analog converters that use the LinEPIC™ 1- μm CMOS process. The TLC5602x converts digital signals to analog signals at a sampling rate of dc to 20 MHz. Because of high-speed operation, the TLC5602x devices are suitable for digital video applications such as digital television, video processing with a computer, and radar-signal processing.

The TLC5602C is characterized for operation from 0°C to 70°C. The TLC5602M is characterized over the full military temperature range of -55°C to 125°C.



NC—No internal connection

LinEPIC is a trademark of Texas Instruments Incorporated.

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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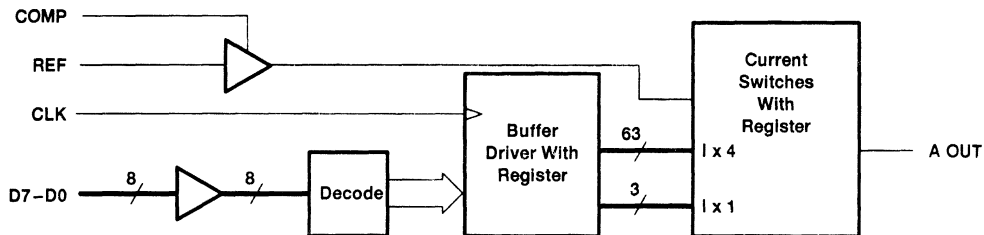
TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023C - FEBRUARY 1989 - REVISED MAY 1995

AVAILABLE OPTIONS

T _A	PACKAGE			
	WIDE-BODY SMALL OUTLINE (DW)	CERAMIC CHIP CARRIER (FK)	CERAMIC DIP (J)	PLASTIC DIP (N)
0°C to 70°C	TLC5602CDW			TLC5602CN
-55°C to 125°C		TLC5602MFK	TLC5602MJ	

functional block diagram

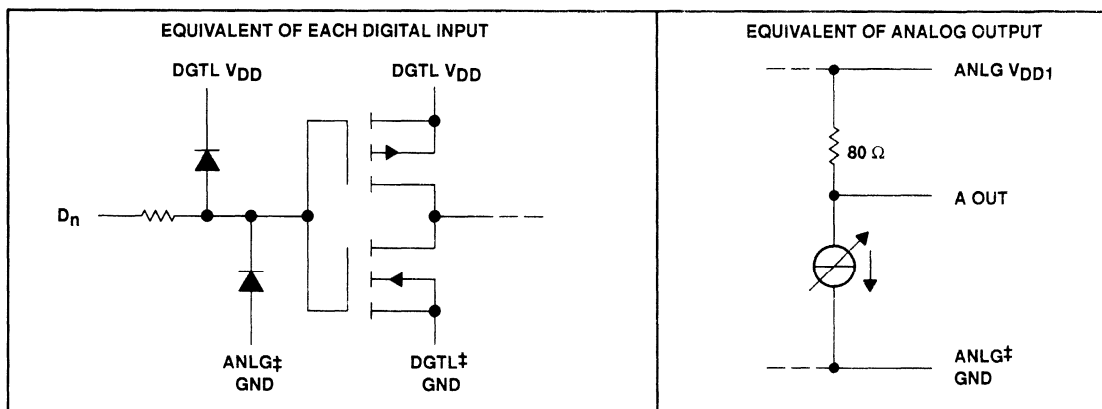


FUNCTION TABLE

STEP	DIGITAL INPUTS								OUTPUT VOLTAGE†
	D7	D6	D5	D4	D3	D2	D1	D0	
0	L	L	L	L	L	L	L	L	3.980 V
1	L	L	L	L	L	L	L	H	3.984 V
127	L	H	H	H	H	H	H	H	4.488 V
128	H	L	L	L	L	L	L	L	4.492 V
129	H	L	L	L	L	L	L	H	4.496 V
254	H	H	H	H	H	H	H	L	4.996 V
255	H	H	H	H	H	H	H	H	5.000 V

† V_{DD} = 5 V and V_{ref} = 4.02 V

schematics of equivalent input and output



‡ ANLG GND and DCTL GND do not connect internally and should be tied together as close to the device terminals as possible.

 **TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023C – FEBRUARY 1989 – REVISED MAY 1995

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, ANLG V_{DD} , DGTL V_{DD}	-0.5 V to 7 V
Digital input voltage range, V_I	-0.5 V to 7 V
Analog reference voltage range, V_{ref}	$V_{DD}-1.7$ V to $V_{DD}+0.5$ V
Operating free-air temperature range, T_A : TLC5602C	0°C to 70°C
TLC5602M	-55°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT	
Supply voltage, V_{DD}	4.75	5	5.25	V	
Analog reference voltage, V_{ref}	3.8	4	4.2	V	
High-level input voltage, V_{IH}	2			V	
Low-level input voltage, V_{IL}			0.8	V	
Pulse duration, CLK high or low, t_w	25			ns	
Setup time, data before CLK↑, t_{su}	16.5			ns	
Hold time, data after CLK↑, t_h	12.5			ns	
Phase compensation capacitance, C_{comp} (see Note 1)	1			μF	
Load resistance, R_L	75k			Ω	
Operating free-air temperature, T_A	TLC5602C		0	70	°C
	TLC5602M		-55	125	

NOTE 1: The phase compensation capacitor should be connected between COMP and ANLG GND.

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP‡	MAX	UNIT		
I_{IH}	High-level input current	Digital inputs $V_I = 5$ V			±1	μA		
I_{IL}	Low-level input current		$V_I = 0$ V			±1	μA	
I_{ref}	Input reference current	$V_{ref} = 4$ V			10	μA		
V_{FS}	Full-scale analog output voltage	$V_{DD} = 5$ V, $V_{ref} = 4.02$ V	$V_{DD}-15$	V_{DD}	$V_{DD}+15$	mV		
V_{ZS}	Zero-scale analog output voltage	$V_{DD} = 5$ V, $V_{ref} = 4.02$ V, $T_A = \text{full range}^{\S}$	TLC5602C	3.919	3.98	4.042	V	
			TLC5602M	3.919	3.98	4.042		
			TLC5602M	3.919	3.98	4.062		
r_o	Output resistance	$T_A = 25^\circ\text{C}$	TLC5602C		60	80	120	Ω
		$T_A = \text{full range}^{\S}$	TLC5602M					
C_i	Input capacitance	$f_{clock} = 1$ MHz, $T_A = 25^\circ\text{C}$		15		pF		
I_{DD}	Supply current	$f_{clock} = 20$ MHz, $V_{ref} = V_{DD}-0.95$ V		16	25	mA		

‡ All typical values are at $V_{DD} = 5$ V and $T_A = 25^\circ\text{C}$.

§ Full range for the TLC5602C is 0°C to 70°C, and full range for the TLC5602M is -55°C to 125°C.



TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023C – FEBRUARY 1989 – REVISED MAY 1995

operating characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
E _{L(adj)}	Linearity error, best-straight-line	T _A = full range‡	TLC5602C			±0.2%	
		T _A = 25°C	TLC5602M			±0.2%	
		T _A = full range‡	TLC5602M			±0.4%	
E _L	Linearity error, end point				±0.15%		
E _D	Linearity error, differential					±0.2%	
G _{diff}	Differential gain	NTSC 40-IRE modulated ramp, f _{clock} = 14.3 MHz, Z _L ≥ 75 kΩ			0.7%		
φ _{diff}	Differential phase	NTSC 40-IRE modulated ramp, f _{clock} = 14.3 MHz, Z _L ≥ 75 kΩ			0.4°		
t _{pd}	Propagation delay time, CLK to analog output	C _L = 10 pF			25		ns
t _s	Settling time to within 1/2 LSB	C _L = 10 pF			30		ns

† All typical values are at V_{DD} = 5 V and T_A = 25°C.

‡ Full range for the TLC5602C is 0°C to 70°C, and full range for the TLC5602M is -55°C to 125°C.

PARAMETER MEASUREMENT INFORMATION

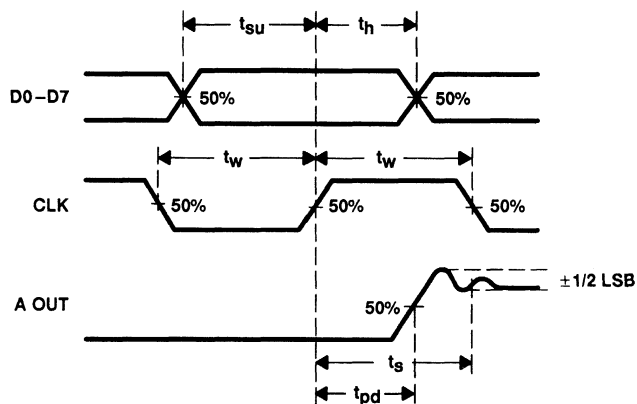


Figure 1. Voltage Waveforms

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023C – FEBRUARY 1989 – REVISED MAY 1995

TYPICAL CHARACTERISTICS

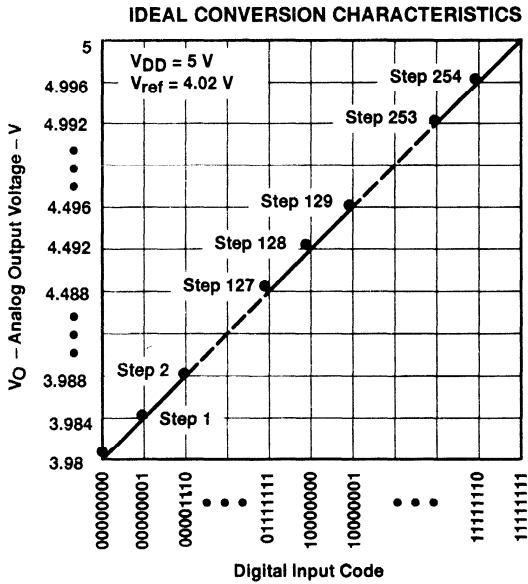


Figure 2

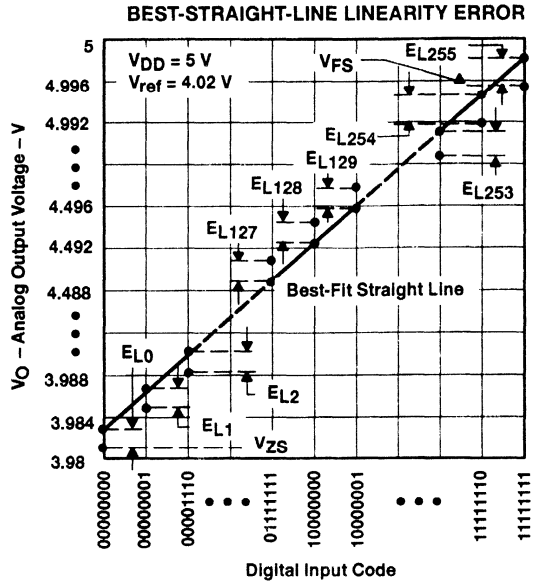
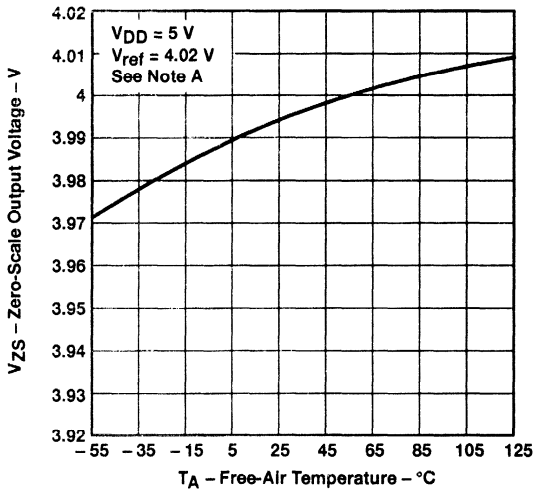


Figure 3

ZERO-SCALE OUTPUT VOLTAGE VS FREE-AIR TEMPERATURE



NOTE A: V_{ref} is relative to ANLG GND. V_{DD} is the voltage between ANLG V_{DD} and DGTL V_{DD} tied together and ANLG GND and DGTL GND tied together.

Figure 4

OUTPUT RESISTANCE VS FREE-AIR TEMPERATURE

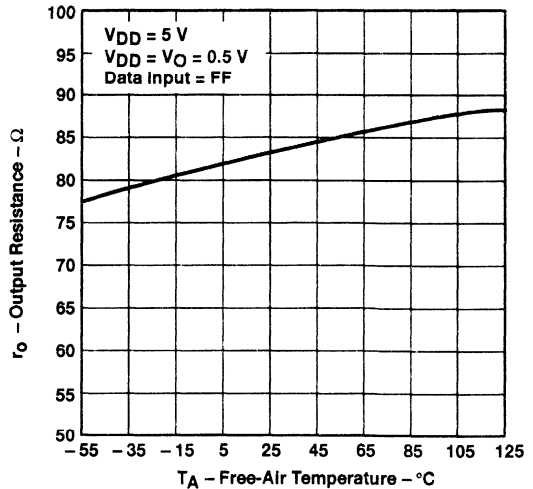


Figure 5

TLC5602C, TLC5602M VIDEO 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS023C – FEBRUARY 1989 – REVISED MAY 1995

TYPICAL CHARACTERISTICS

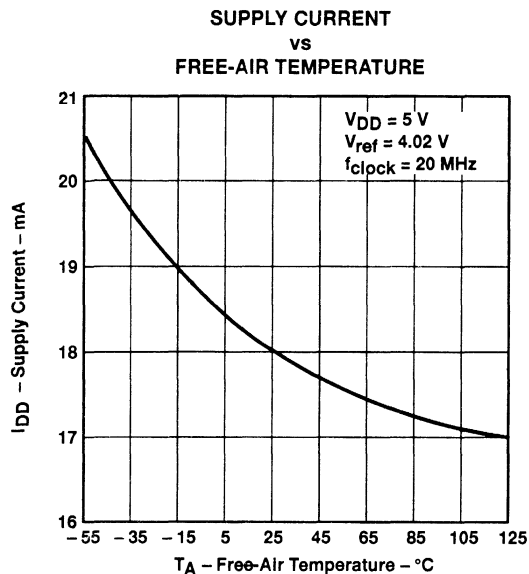
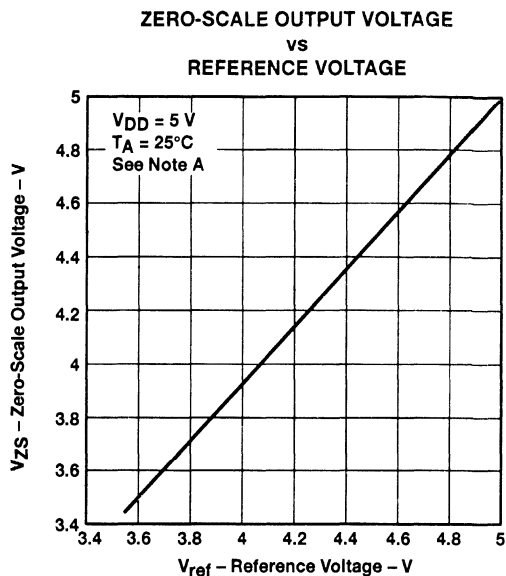


Figure 6



NOTE A: V_{ref} is relative to ANLG GND. V_{DD} is the voltage between ANLG V_{DD} and DGTL V_{DD} tied together and ANLG GND and DGTL GND tied together.

Figure 7

APPLICATION INFORMATION

The following design recommendations benefit the TLC5602 user:

- Physically separate and shield external analog and digital circuitry as much as possible to reduce system noise.
- Use RF breadboarding or RF printed-circuit-board (PCB) techniques throughout the evaluation and production process.
- Since ANLG GND and DGTL GND are not connected internally, these terminals need to be connected externally. With breadboards, these ground lines should connect to the power-supply ground through separate leads with proper supply bypassing. A good method is to use a separate twisted pair for the analog and digital supply lines to minimize noise pickup.

Use wide ground leads or a ground plane on the PCB layouts to minimize parasitic inductance and resistance. The ground plane is the better choice for noise reduction.

- ANLG V_{DD} and DGTL V_{DD} are also separated internally, so they must connect externally. These external PCB leads should also be made as wide as possible. Place a ferrite bead or equivalent inductance in series with ANLG V_{DD} and the decoupling capacitor as close to the device terminals as possible before the ANLG V_{DD} and DGTL V_{DD} leads are connected together on the board.
- Decouple ANLG V_{DD} to ANLG GND and DGTL V_{DD} to DGTL GND with a 1- μ F and 0.01- μ F capacitor, respectively, as close as possible to the appropriate device terminals. A ceramic chip capacitor is recommended for the 0.01- μ F capacitor.
- Connect the phase compensation capacitor between COMP and ANLG GND with as short a lead-in as possible.
- The no-connection (NC) terminals on the small-outline package should be connected to ANLG GND.
- Shield ANLG V_{DD} , ANLG GND, and A OUT from the high-frequency terminals CLK and D7–D0. Place ANLG GND traces on both sides of the A OUT trace on the PCB.

TL5632C

8-BIT 3-CHANNEL HIGH-SPEED DIGITAL-TO-ANALOG CONVERTER

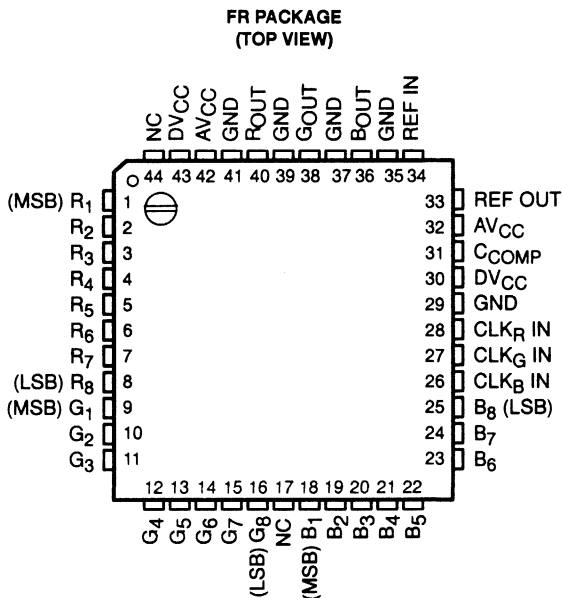
SLAS091 – DECEMBER 1994

- 8-Bit Resolution
- Linearity . . . $\pm 1/2$ LSB Maximum
- Differential Nonlinearity . . . $\pm 1/2$ LSB Maximum
- Conversion Rate . . . 60 MHz Min
- Nominal Output Signal Operating Range V_{CC} to $V_{CC} - 1$ V
- TTL Digital Input Voltage
- 5-V Single Power Supply Operation
- Low Power Consumption . . . 350 mW Typ

description

The TL5632C is a low-power ultra-high-speed video digital-to-analog converter that uses the Advanced Low-Power Schottky (ALS) process. The device has a three channel I/O; the red, the blue, and the green channel. The red, blue, and green signals are referred to collectively as the RGB signal. An internally generated reference is also provided for the standard video output voltage range. Conversion of digital signals to analog signals can be at a sampling rate of dc to 60 MHz. The high conversion rate makes the TL5632C suitable for digital television, computer digital video processing, and high-speed data conversion.

The TL5632C is characterized for operation from 0°C to 70°C.



NC – No internal connection

FUNCTION TABLE

STEP	DIGITAL INPUT	OUTPUT VOLTAGE
0	LLLLLLLLL	3.980 V
1	LLLLLLLLH	3.984 V
•	•	•
•	•	•
•	•	•
127	LHHHHHHH	4.488 V
128	HLLLLLLLL	4.492 V
129	HLLLLLLLLH	4.996 V
•	•	•
•	•	•
•	•	•
254	HHHHHHHL	4.996 V
255	HHHHHHHH	5.000 V

AVAILABLE OPTIONS

T _A	PACKAGE
0°C to 70°C	TL5632CFR

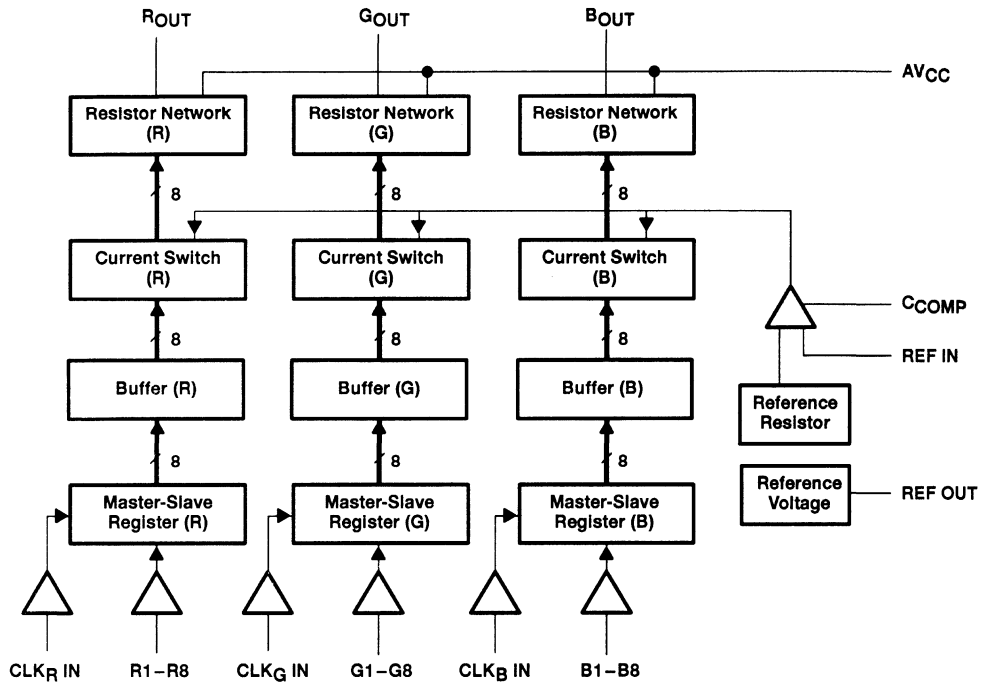
PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



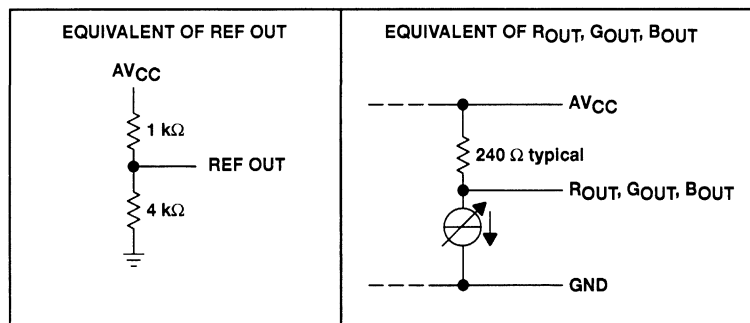
TL5632C 8-BIT 3-CHANNEL HIGH-SPEED DIGITAL-TO-ANALOG CONVERTER

SLAS091 – DECEMBER 1994

functional block diagram



schematics of outputs



TL5632C

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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
B ₁ – B ₈	18 – 25	I	B-channel digital input (B ₁ = MSB)
B _{OUT}	36	O	B-channel analog output
C _{COMP}	31		Phase compensation capacitance. A 1 μF capacitor is connected from C _{COMP} to GND.
CLK _B IN	26	I	B-channel clock input
CLK _G IN	27	I	G-channel clock input
CLK _R IN	28	I	R-channel clock input
G ₁ – G ₈	9 – 16	I	G-Channel digital input (G ₁ = MSB)
GND	29, 35, 37, 39, 41		Ground. All GND terminals are connected internally; however, all GND terminals should be connected externally to a ground plane or equivalent low impedance ground return.
G _{OUT}	38	O	G-channel analog output
NC	17, 44		No connection internally
R ₁ – R ₈	1 – 8	I	R-channel digital input (R ₁ = MSB)
R _{OUT}	40	O	R-channel analog output
AV _{CC}	32, 42		Analog power supply voltage
DV _{CC}	30, 43		Digital power supply voltage
REF IN	34	I	Reference voltage input. REF IN accepts the reference voltage on REF OUT. An external reference can also be applied consistent with Note 1.
REF OUT	33	O	Reference voltage output. An internal voltage divider generates the voltage level (see schematics of outputs, page 2).

NOTE 1: $V_{CC} - V_{ref} \leq 1.2 \text{ V}$

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Power supply voltage range, AV _{CC} , DV _{CC} (see Note 2)	–0.3 V to 7 V
Digital input voltage range, V _I	–0.3 V to DV _{CC}
Analog output voltage range, R _{OUT} , G _{OUT} , B _{OUT} , C _{COMP} (externally applied)	–0.3 V to AV _{CC} + 0.3 V
Reference input range, REF IN	–0.3 V to AV _{CC} + 0.3 V
Reference output range, REF OUT	–0.3 V to AV _{CC} + 0.3 V
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range	–65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 2: All voltage values are with respect to GND.

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recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC} , DV_{CC}	4.75	5	5.25	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
Reference voltage, V_{ref} (see Note 1)	3.8	4	4.2	V
Setup time, data before $CLK\uparrow$, t_{SU1}	10			ns
Hold time, data after $CLK\uparrow$, t_{H1}	3			ns
Pulse duration at high level, t_{W1}	8.3			ns
Pulse duration at low level, t_{W2}	8.3			ns
External phase compensation capacitance, C_{COMP}	1			μ F
Operating free-air temperature, T_A	0		70	$^{\circ}$ C

NOTE 1: $V_{CC} - V_{ref} \leq 1.2$ V

electrical characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Resolution				8	Bit
I_{IH} High-level input current	$V_{CC} = 5.25$ V, $V_{IH} = 2.7$ V			20	μ A
I_{IL} Low-level input current	$V_{CC} = 5.25$ V, $V_{IH} = 2.7$ V	-400			μ A
I_{ref} Reference input current	REF IN = 4 V			10	μ A
V_{ref} Reference output voltage	$V_{CC} = 5$ V, With internal reference	3.8	4	4.2	V
V_{FS} Full-scale analog output voltage	$V_{IH} = 2$ V, REF IN = 4 V	$AV_{CC}-15$	AV_{CC}	$AV_{CC}+15$	mV
V_{ZS} Zero-scale analog output voltage	$V_{IL} = 0.8$ V, REF IN = 4 V	3.9	3.98	4.05	V
RGB full-scale ratio		0%	4%	8%	
z_o Output impedance		200	240	280	Ω
I_{CC} Supply current			70	90	mA

operating characteristics over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
E_L Linearity error	End point, REF IN = 4 V			± 0.5	LSB
E_D Differential linearity error	REF IN = 4 V			± 0.5	LSB
f_c Maximum conversion rate		60			MHz
t_{PLH} Propagation delay time, low-to-high level	$T_A = 25^{\circ}$ C, $C_L \leq 5$ pF‡		10		ns
t_{PHL} Propagation delay time, high-to-low level			10		
t_r Rise time			5		ns
t_f Fall time			5		

† All typical values are at $V_{CC} = 5$ V, $T_A = 25^{\circ}$ C.

‡ C_L includes probe and jig capacitances.

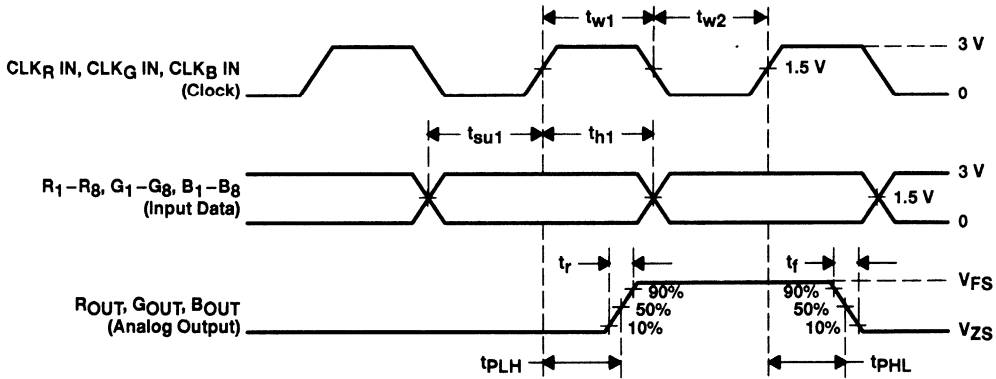


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PARAMETER MEASUREMENT INFORMATION



TYPICAL CHARACTERISTICS

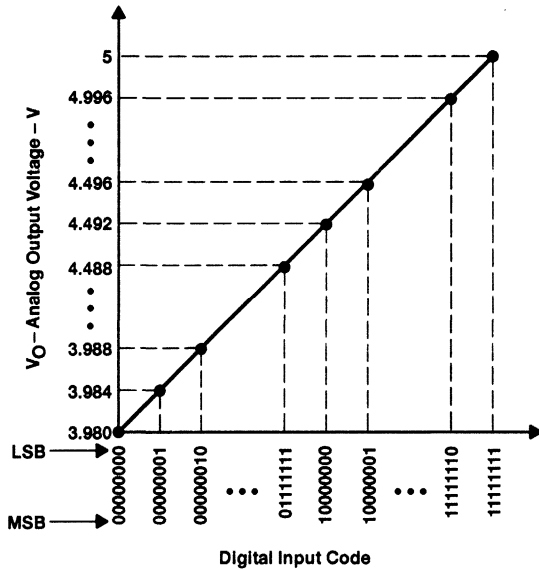


Figure 1. Ideal Conversion Characteristics

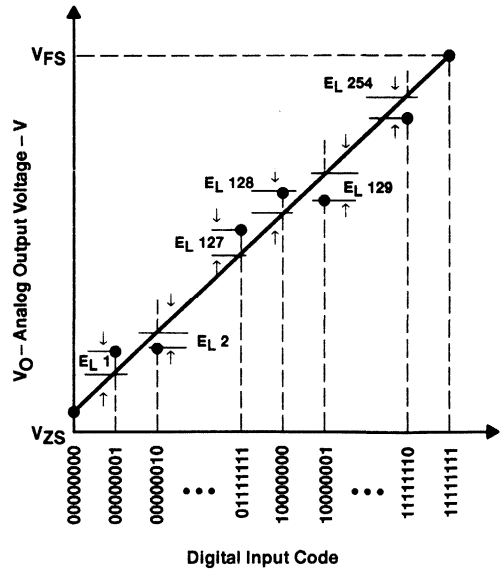


Figure 2. End-Point Linearity Error

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APPLICATION INFORMATION

The following design procedures should be used for optimum operation.

- External analog and digital circuitry should be physically separated and shielded as much as possible to reduce system noise.
- RF breadboarding or RF printed-circuit-board (PCB) techniques should be used throughout the evaluation and production process.
- Wide ground leads or a ground plane should be used on the PCB layouts to minimize parasitic inductance and resistance. A ground plane is the better choice for noise reduction.
- AV_{CC} and DV_{CC} are also separate internally, so they must be connected externally. These external PCB leads should also be made as wide as possible. A ferrite bead or equivalent inductance should be placed in series with AV_{CC} and the decoupling capacitor before the AV_{CC} and DV_{CC} leads are connected together on the board. It is critical that the supply voltage applied to AV_{CC} be as noise free and ripple free as possible. Ripple and noise rejection should be a minimum of 60 dB below the full-scale output range of 1 V peak-to-peak.
- AV_{CC} to GND and DV_{CC} to GND should be decoupled with 3.3- μ F and 0.1- μ F capacitors, respectively, as close as possible to the appropriate device terminals. A ceramic chip capacitor is recommended for the 0.1- μ F capacitor.
- The phase compensation capacitor should be connected between C_{COMP} and GND with as short a lead-in as possible.
- The no-connection (NC) terminals on the small-outline package should be connected to GND.
- AV_{CC} , DV_{CC} , and R_{OUT} , G_{OUT} , and B_{OUT} should be shielded from the high-frequency terminals $CLK_R IN$, $CLK_G IN$, and $CLK_B IN$ and the input data terminals. GND traces should be placed on both sides of the R_{OUT} , G_{OUT} , and B_{OUT} traces on the PCB to the following signal processing stage. These output traces should be as short as possible.

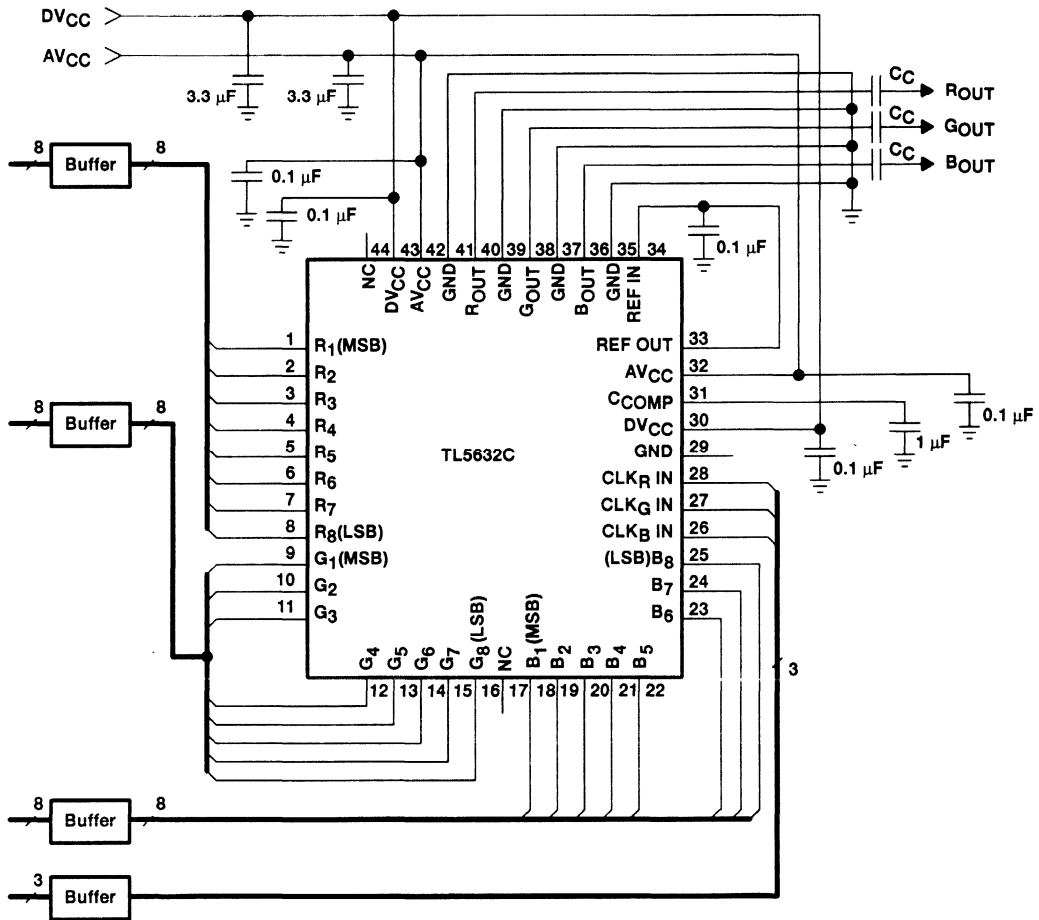


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APPLICATION INFORMATION



- NOTES:
- Buffers are SN74AS244 or equivalent.
 - 0.1 μF capacitors should be placed as close to the device terminals as possible.
 - The coupling capacitor (C_C) value is application specific and selectable by the user.

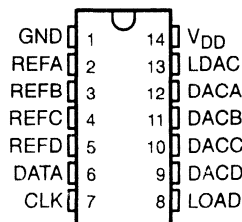
Figure 3. Typical Bypass, Buffer, and Output Configuration

TLC5620C, TLC5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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- Four 8-Bit Voltage Output DACs
- 5-V Single-Supply Operation
- Serial Interface
- High-Impedance Reference Inputs
- Programmable 1 or 2 Times Output Range
- Simultaneous-Update Facility
- Internal Power-On Reset
- Low Power Consumption
- Half-Buffered Output

N OR D PACKAGE
(TOP VIEW)



applications

- Programmable Voltage Sources
- Digitally-Controlled Amplifiers/Attenuators
- Mobile Communications
- Automatic Test Equipment
- Process Monitoring and Control
- Signal Synthesis

description

The TLC5620C and TLC5620I are quadruple 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND, and the DACs are monotonic. The device is simple to use, running from a single supply of 5 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLC5620C and TLC5620I are over a simple 3-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 11-bit command word comprises 8 bits of data, 2 DAC select bits and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs updated simultaneously through control of the LDAC terminal. The digital inputs feature Schmitt triggers for high noise immunity.

The 14-terminal small-outline (SO) package allows digital control of analog functions in space-critical applications. The TLC5620C is characterized for operation from 0°C to 70°C. The TLC5620I is characterized for operation from -40°C to 85°C. The TLC5620C and TLC5620I do not require external trimming.

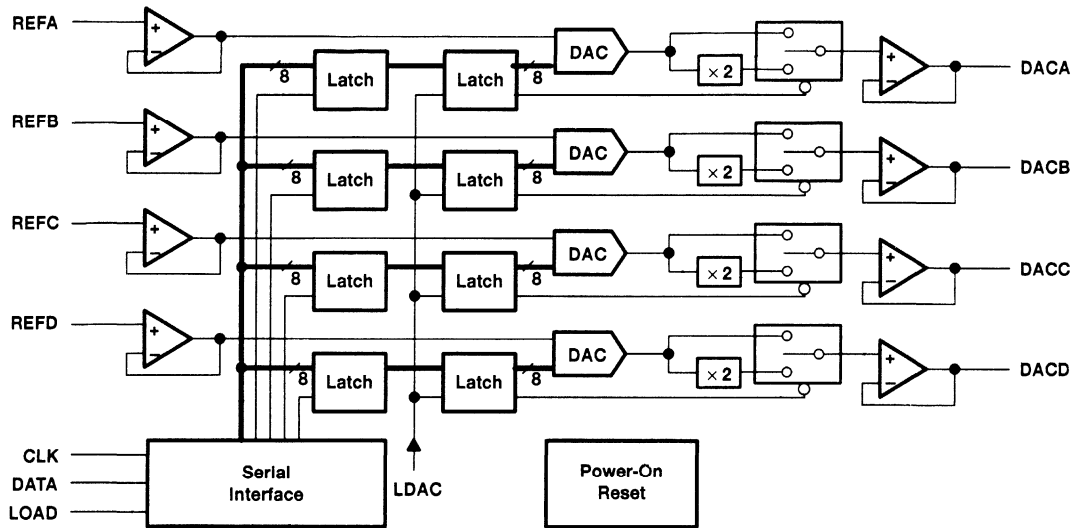
AVAILABLE OPTIONS

T _A	PACKAGE	
	SMALL OUTLINE (D)	PLASTIC DIP (N)
0°C to 70°C	TLC5620CD	TLC5620CN
-40°C to 85°C	TLC5620ID	TLC5620IN

TLC5620C, TLC5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
CLK	7	I	Serial-interface clock, data enters on the negative edge
DACA	12	O	DAC A analog output
DACB	11	O	DAC B analog output
DACC	10	O	DAC C analog output
DACD	9	O	DAC D analog output
DATA	6	I	Serial-interface digital-data input
GND	1	I	Ground return and reference terminal
LDAC	13	I	DAC-update latch control
LOAD	8	I	Serial-interface load control
REFA	2	I	Reference voltage input to DACA
REFB	3	I	Reference voltage input to DACB
REFC	4	I	Reference voltage input to DACC
REFD	5	I	Reference voltage input to DACD
VDD	14	I	Positive supply voltage

detailed description

The TLC5620 is implemented using four resistor-string digital-to-analog converters (DACs). The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 2. One end of each resistor string is connected to the GND terminal and the other end is fed from the output of the reference input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor elements and upon the performance of the output buffer. Because the inputs are buffered, the DACs always presents a high-impedance load to the reference source.



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detailed description (continued)

Each DAC output is buffered by a configurable-gain output amplifier, which can be programmed to times 1 or times 2 gain.

On powerup, the DACs are reset to CODE 0.

Each output voltage is given by:

$$V_O(\text{DACAIBICID}) = \text{REF} \times \frac{\text{CODE}}{256} \times (1 + \text{RNG bit value})$$

where CODE is in the range 0 to 255 and the range (RNG) bit is a 0 or 1 within the serial-control word.

data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial-input register to the selected DAC as shown in Figure 1. If LDAC is low, the selected DAC output voltage is updated and LOAD goes low. If LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered MSB first.

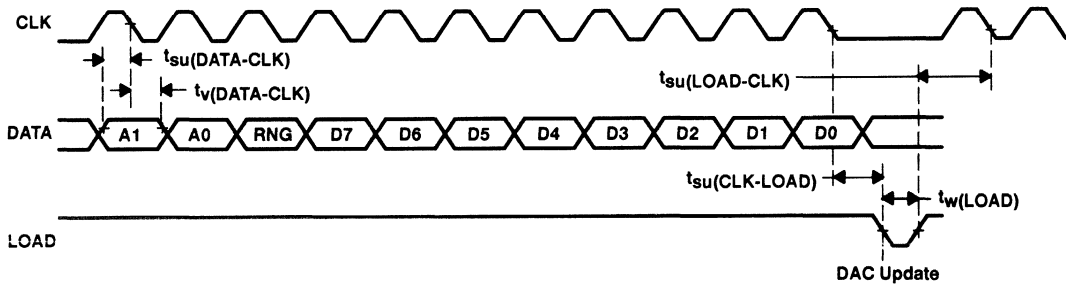


Figure 1. LOAD-Controlled Update (LDAC = Low)

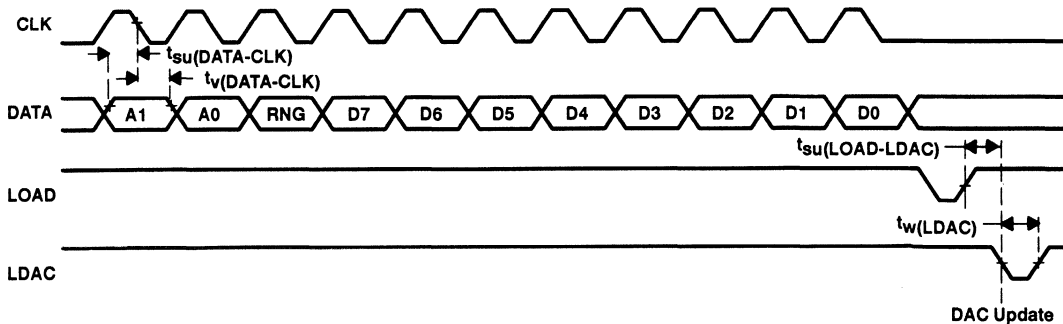


Figure 2. LDAC-Controlled Update

data interface (continued)

Table 1 lists the A1 and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

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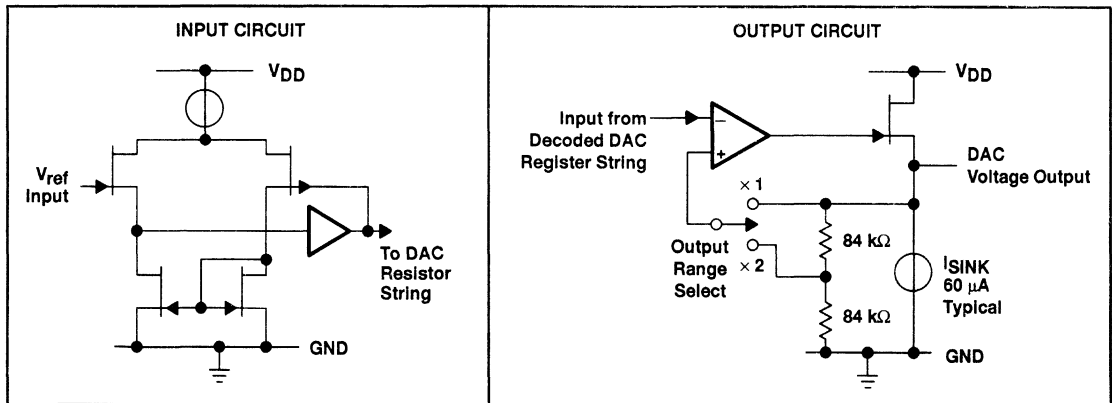
Table 1. Serial-Input Decode

A1	A0	DAC UPDATED
0	0	DACA
0	1	DACB
1	0	DACC
1	1	DACD

Table 2. Ideal-Output Transfer

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	$(1/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	$(127/256) \times \text{REF} (1+\text{RNG})$
1	0	0	0	0	0	0	0	$(128/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	$(255/256) \times \text{REF} (1+\text{RNG})$

equivalent inputs and outputs



TLC5620C, TLC5620I

QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage ($V_{DD} - GND$)	7 V
Digital input voltage range	$GND - 0.3 V$ to $V_{DD} + 0.3 V$
Reference input voltage range, V_{ID}	$GND - 0.3 V$ to $V_{DD} + 0.3 V$
Operating free-air temperature range, T_A : TLC5620C	0°C to 70°C
TLC5620I	-40°C to 85°C
Storage temperature range, T_{stg}	-50°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	230°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	4.75		5.25	V
High-level digital input voltage, V_{IH}	0.8 V_{DD}			V
Low-level digital input voltage, V_{IL}	0.8			V
Reference voltage, V_{ref} [AIBICID]	$V_{DD} - 1.5$			V
Load resistance, R_L	10			k Ω
Setup time, data input, $t_{su}(DATA-CLK)$ (see Figures 1 and 2)	50			ns
Valid time, data input valid after $CLK\downarrow$, $t_v(DATA-CLK)$ (see Figures 1 and 2)	50			ns
Setup time, CLK 11th falling edge to LOAD, $t_{su}(CLK-LOAD)$ (see Figure 1)	50			ns
Setup time, $LOAD\uparrow$ to $CLK\downarrow$, $t_{su}(LOAD-CLK)$ (see Figure 1)	50			ns
Pulse duration, LOAD, $t_w(LOAD)$ (see Figure 1)	250			ns
Pulse duration, LDAC, $t_w(LDAC)$ (see Figure 1)	250			ns
Setup time, $LOAD\uparrow$ to $LDAC\downarrow$, $t_{su}(LOAD-LDAC)$ (see Figure 1)	0			ns
CLK frequency				1 MHz
Operating free-air temperature, T_A	TLC5620C		70	°C
	TLC5620I		-40	85 °C



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electrical characteristics over recommended operating free-air temperature range, $V_{DD} = 5\text{ V} \pm 5\%$, $V_{ref} = 2\text{ V}$, $\times 1$ gain output range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level digital input current	$V_I = V_{DD}$			± 10	μA
I_{IL}	Low-level digital input current	$V_I = 0\text{ V}$			± 10	μA
$I_{O(sink)}$	Output sink current	Each DAC output	20			μA
$I_{O(source)}$	Output source current		2			mA
C_i	Input capacitance			15		pF
	Reference input capacitance			15		
I_{DD}	Supply current	$V_{DD} = 5\text{ V}$			2	mA
I_{ref}	Reference input current	$V_{DD} = 5\text{ V}$, $V_{ref} = 2\text{ V}$			± 10	μA
E_L	Linearity error (end point corrected)	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 1)			± 1	LSB
E_D	Differential-linearity error	$V_{ref} = 2\text{ V}$, $\times 1$ gain (see Note 2)			± 0.9	LSB
E_{ZS}	Zero-scale error	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 3)	0		30	mV
	Zero-scale error temperature coefficient	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 4)		10		$\mu\text{V}/^\circ\text{C}$
E_{FS}	Full-scale error	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 5)			± 60	mV
	Full-scale error temperature coefficient	$V_{ref} = 2\text{ V}$, $\times 2$ gain (see Note 6)		± 25		$\mu\text{V}/^\circ\text{C}$
PSRR	Power-supply sensitivity	See Notes 7 and 8		0.5		mV/V

- NOTES: 1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero and full scale (excluding the effects of zero code and full-scale errors).
2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
4. Zero-scale error temperature coefficient is given by: $ZSETC = [ZSE(T_{max}) - ZSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
5. Full-scale error is the deviation from the ideal full-scale output ($V_{ref} - 1$ LSB) with an output load of 10 k Ω .
6. Full-scale temperature coefficient is given by: $FSETC = [FSE(T_{max}) - FSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
7. Zero-scale error rejection ratio (ZSE-RR) is measured by varying the V_{DD} voltage from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
8. Full-scale error rejection ratio (FSE-RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

operating characteristics over recommended operating free-air temperature range, $V_{DD} = 5\text{ V} \pm 5\%$, $V_{ref} = 2\text{ V}$, $\times 1$ gain output range (unless otherwise noted)

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	$C_L = 100\text{ pF}$, $R_L = 10\text{ k}\Omega$		1		$\text{V}/\mu\text{s}$
Output settling time	To 0.5 LSB, $C_L = 100\text{ pF}$, $R_L = 10\text{ k}\Omega$, See Note 9		10		μs
Large-signal bandwidth	Measured at -3 dB point		100		kHz
Digital crosstalk	$\text{CLK} = 1\text{-MHz}$ square wave measured at DACA-DACD		-50		dB
Reference feedthrough	See Note 10		-60		dB
Channel-to-channel isolation	See Note 11		-60		dB
Reference input bandwidth	See Note 12		100		kHz

- NOTES: 9. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of 00 hex to FF hex or FF hex to 00 hex. For TLC5620C: $V_{DD} = 5\text{ V}$, $V_{ref} = 2\text{ V}$ and range = $\times 2$. For TLC5620I: $V_{DD} = 3\text{ V}$, $V_{ref} = 1.25\text{ V}$ and range $\times 2$.
10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex with V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
12. Reference bandwidth is the -3 dB bandwidth with an input at $V_{ref} = 1.25\text{ V}$ dc + 2 V_{pp} , with a digital input code of full-scale.



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PARAMETER MEASUREMENT INFORMATION

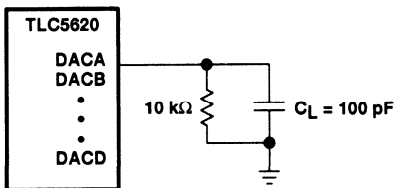


Figure 3. Slewing Settling Time and Linearity Measurements

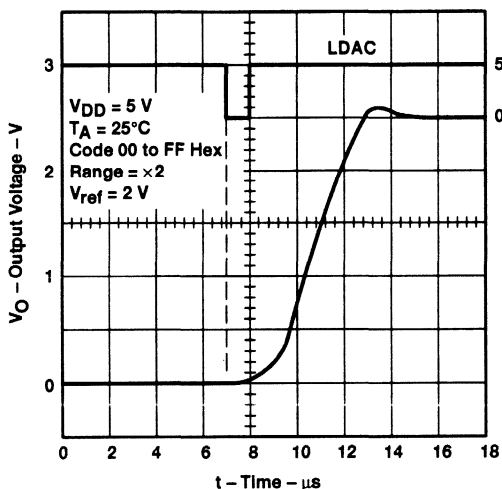


Figure 4. Positive Rise and Settling Time $V_{DD} = 5\text{ V}$

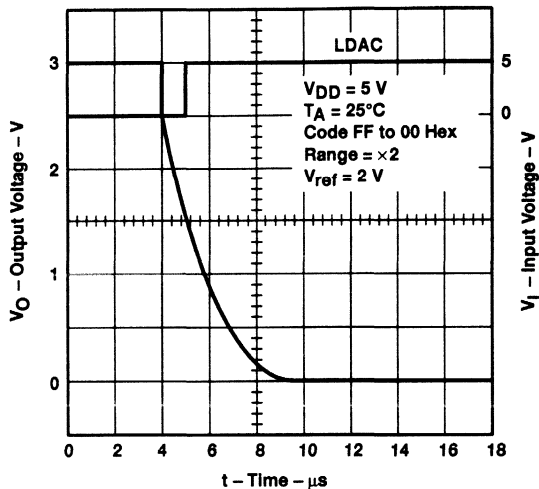
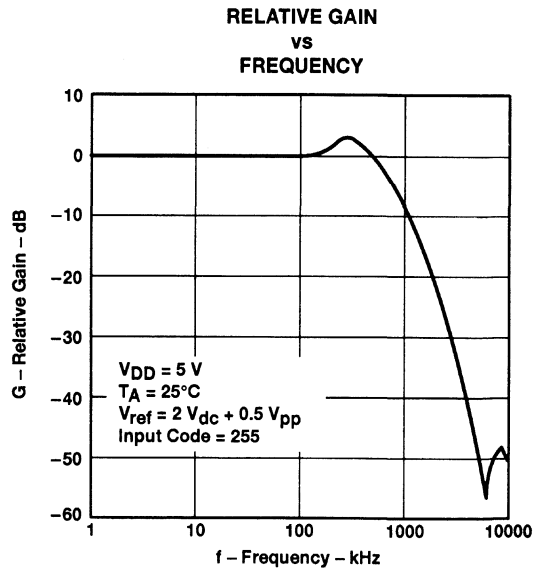
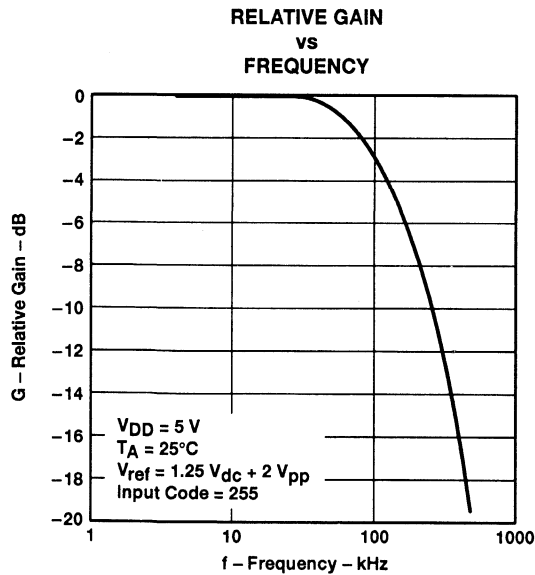
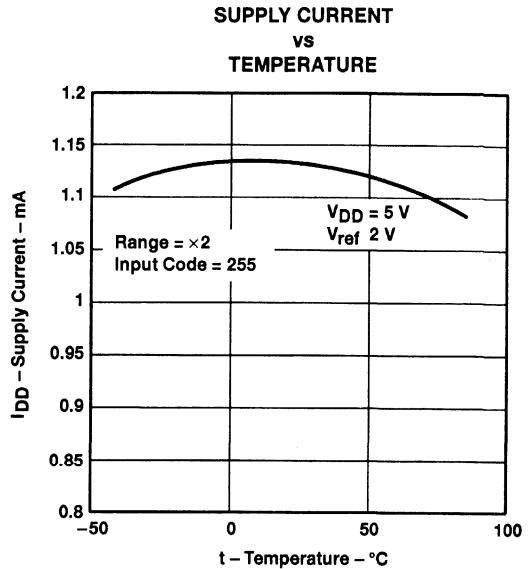
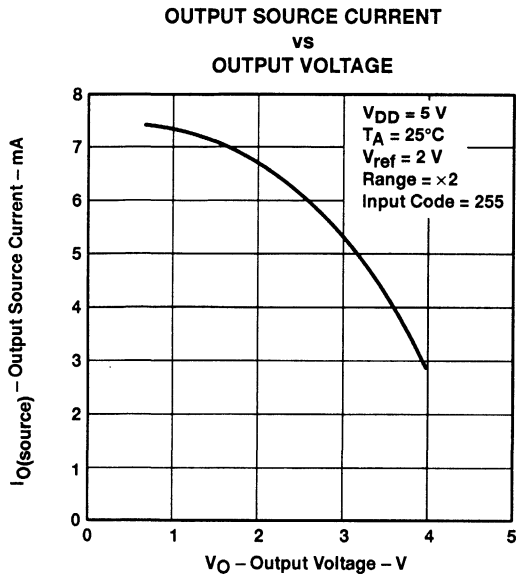


Figure 5. Negative Fall and Settling Time $V_{DD} = 5\text{ V}$

TLC5620C, TLC5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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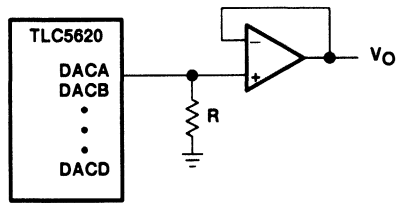
TYPICAL CHARACTERISTICS



TLC5620C, TLC5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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APPLICATION INFORMATION



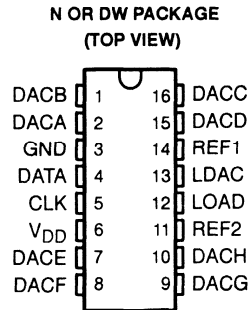
NOTE A: Resistor $R \geq 10 \text{ k}\Omega$

Figure 10. Output Buffering Schemes

TLC5628C, TLC5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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- Eight 8-Bit Voltage Output DACs
- 5-V Single-Supply Operation
- Serial Interface
- High-Impedance Reference Inputs
- Programmable 1 or 2 Times Output Range
- Simultaneous-Update Facility
- Internal Power-On Reset
- Low Power Consumption
- Half-Buffered Output



applications

- Programmable Voltage Sources
- Digitally-Controlled Amplifiers/Attenuators
- Mobile Communications
- Automatic Test Equipment
- Process Monitoring and Control
- Signal Synthesis

description

The TLC5628C and TLC5628I are octal 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND and are monotonic. The device is simple to use, running from a single supply of 5 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLC5628C and TLC5628I are over a simple 3-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 12-bit command word comprises 8 bits of data, 3 DAC select bits and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs updated simultaneously through control of the LDAC terminal. The digital inputs feature Schmitt triggers for high noise immunity.

The 16-terminal small-outline (DW) package allows digital control of analog functions in space-critical applications. The TLC5628C is characterized for operation from 0°C to 70°C. The TLC5628I is characterized for operation from -40°C to 85°C. The TLC5628C and TLC5628I do not require external trimming.

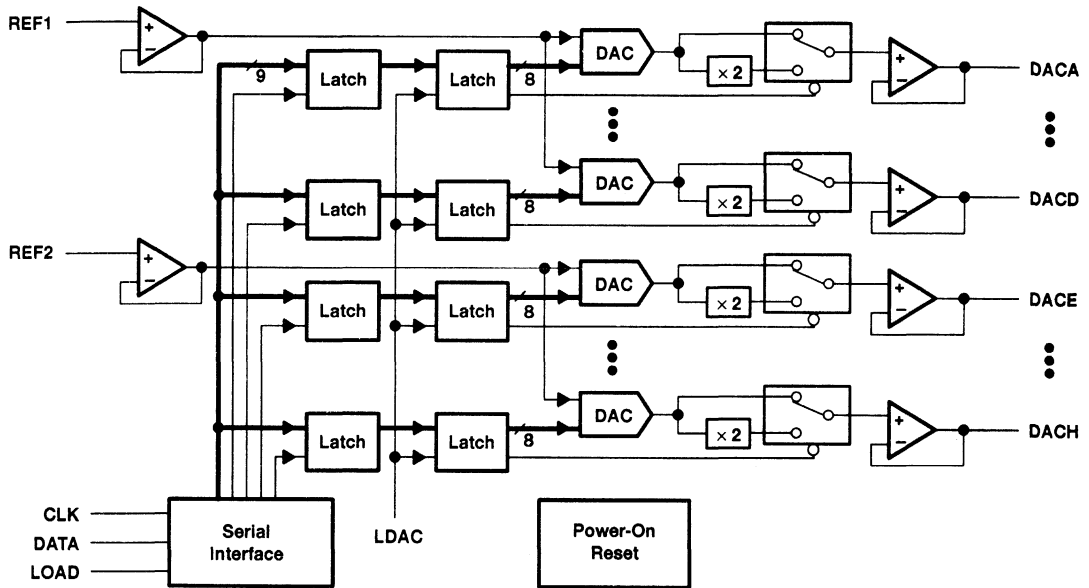
AVAILABLE OPTIONS

T _A	PACKAGE	
	SMALL OUTLINE (DW)	PLASTIC DIP (N)
0°C to 70°C	TLC5628CDW	TLC5628CN
-40°C to 85°C	TLC5628IDW	TLC5628IN

TLC5628C, TLC5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
CLK	5	I	Serial-interface clock, data enters on the negative edge
DACA	2	O	DACA analog output
DACB	1	O	DACB analog output
DACC	16	O	DACC analog output
DACD	15	O	DACD analog output
DACE	7	O	DACE analog output
DACF	8	O	DACF analog output
DACG	9	O	DACG analog output
DACH	10	O	DACH analog output
DATA	4	I	Serial-interface digital data input
GND	3	I	Ground return and reference terminal
LDAC	13	I	DAC-update latch control
LOAD	12	I	Serial-interface load control
REF1	14	I	Reference voltage input to DACA
REF2	11	I	Reference voltage input to DACB
V _{DD}	6	I	Positive supply voltage

detailed description

The TLC5628 is implemented using eight resistor-string digital-to-analog converters (DACs). The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 2. One end of each resistor string is connected to the GND terminal and the other end is fed from the output of the reference

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input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor elements and upon the performance of the output buffer. Because the inputs are buffered, the DACs always present a high-impedance load to the reference sources. There are two input reference terminals; REF1 is used for DACA through DACD and REF2 is used by DACE through DACH.

Each DAC output is buffered by a configurable-gain output amplifier, which can be programmed to times 1 or times 2 gain.

On powerup, the DACs are reset to CODE 0.

Each output voltage is given by:

$$V_O(\text{DACAIBICIDIEFIGIH}) = \text{REF} \times \frac{\text{CODE}}{256} \times (1 + \text{RNG bit value})$$

where CODE is in the range 0 to 255 and the range (RNG) bit is a 0 or 1 within the serial-control word.

data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial-input register to the selected DAC as shown in Figure 1. If LDAC is low, the selected DAC output voltage is updated and LOAD goes low. If LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered MSB first.

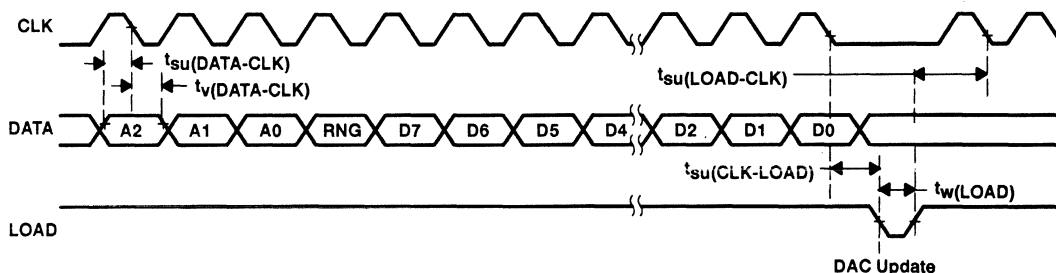


Figure 1. LOAD-Controlled Update (LDAC = Low)

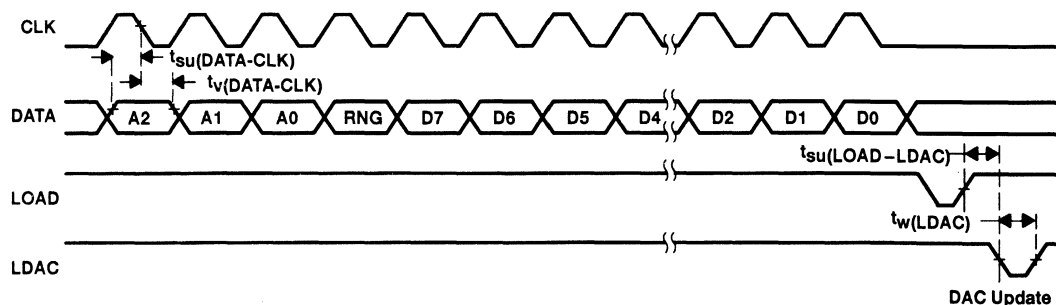


Figure 2. LDAC-Controlled Update

data interface (continued)

Table 1 lists the A1 and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

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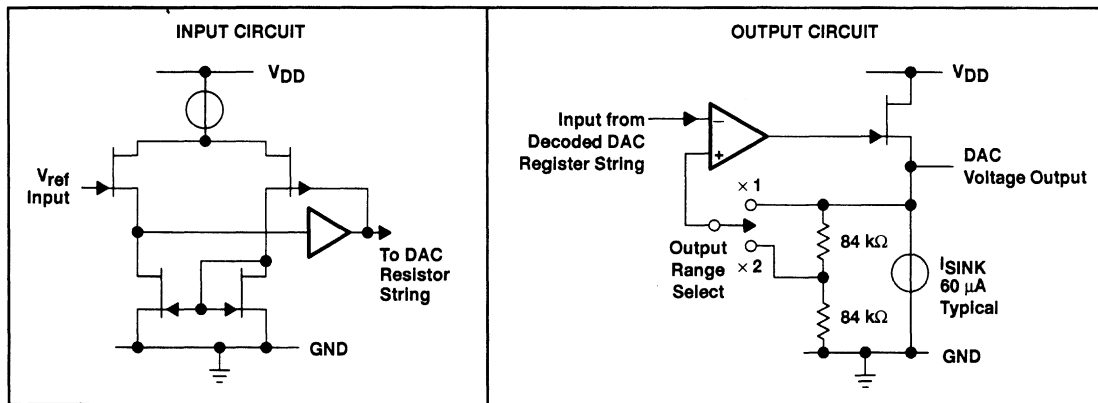
Table 1. Serial-Input Decode

A2	A1	A0	DAC UPDATED
0	0	0	DACA
0	0	1	DACB
0	1	0	DACC
0	1	1	DACD
1	0	0	DACE
1	0	1	DACF
1	1	0	DACG
1	1	1	DACH

Table 2. Ideal-Output Transfer

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	$(1/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	$(127/256) \times \text{REF} (1+\text{RNG})$
1	0	0	0	0	0	0	0	$(128/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	$(255/256) \times \text{REF} (1+\text{RNG})$

equivalent of inputs and outputs



TLC5628C, TLC5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage ($V_{DD} - GND$)	7 V
Digital input voltage range, V_{ID}	$GND - 0.3 V$ to $V_{DD} + 0.3 V$
Reference input voltage range	$GND - 0.3 V$ to $V_{DD} + 0.3 V$
Operating free-air temperature range, T_A : TLC5628C	$0^{\circ}C$ to $70^{\circ}C$
TLC5628I	$-40^{\circ}C$ to $85^{\circ}C$
Storage temperature range, T_{stg}	$-50^{\circ}C$ to $150^{\circ}C$
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	$230^{\circ}C$

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	MAX	UNIT
Supply voltage, V_{DD}	4.75	5.25	V
High-level digital input voltage, V_{IH}	$0.8 V_{DD}$		V
Low-level digital input voltage, V_{IL}		0.8	V
Reference voltage, V_{ref} [AIBICIDIEIFIGIH]		$V_{DD} - 1.5$	V
Load resistance, R_L	10		$k\Omega$
Setup time, data input, $t_{su}(DATA-CLK)$ (see Figures 1 and 2)	50		ns
Valid time, data input valid after $CLK\downarrow$, $t_v(DATA-CLK)$ (see Figures 1 and 2)	50		ns
Setup time, CLK 11th falling edge to $LOAD$, $t_{su}(CLK-LOAD)$ (see Figure 1)	50		ns
Setup time, $LOAD\uparrow$ to $CLK\downarrow$, $t_{su}(LOAD-CLK)$ (see Figure 1)	50		ns
Pulse duration, $LOAD$, $t_w(LOAD)$ (see Figure 1)	250		ns
Pulse duration, $LDAC$, $t_w(LDAC)$ (see Figure 2)	250		ns
Setup time, $LOAD\uparrow$ to $LDAC\downarrow$, $t_{su}(LOAD-LDAC)$ (see Figure 2)	0		ns
CLK frequency		1	MHz
Operating free-air temperature, T_A	TLC5628C	0	$70^{\circ}C$
	TLC5628I	-40	$85^{\circ}C$

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electrical characteristics over recommended operating free-air temperature range, $V_{DD} = 5 V \pm 5\%$, $V_{ref} = 2 V$, $\times 1$ gain output range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level digital input current	$V_I = V_{DD}$			± 10	μA
I_{IL}	Low-level digital input current	$V_I = 0 V$			± 10	μA
$I_{O(sink)}$	Output sink current	Each DAC output		20		μA
$I_{O(source)}$	Output source current			2		mA
C_i	Input capacitance			15		pF
	Reference input capacitance			15		
I_{DD}	Supply current	$V_{DD} = 5 V$			4	mA
I_{ref}	Reference input current	$V_{DD} = 5 V$, $V_{ref} = 2 V$			± 10	μA
E_L	Linearity error (end point corrected)	$V_{ref} = 2 V$, $\times 2$ gain (see Note 1)			± 1	LSB
E_D	Differential-linearity error	$V_{ref} = 2 V$, $\times 2$ gain (see Note 2)			± 0.9	LSB
E_{ZS}	Zero-scale error	$V_{ref} = 2 V$, $\times 2$ gain (see Note 3)	0		30	mV
	Zero-scale error temperature coefficient	$V_{ref} = 2 V$, $\times 2$ gain (see Note 4)		10		$\mu V/^\circ C$
E_{FS}	Full-scale error	$V_{ref} = 2 V$, $\times 2$ gain (see Note 5)			± 60	mV
	Full-scale error temperature coefficient	$V_{ref} = 2 V$, $\times 2$ gain (see Note 6)		± 25		$\mu V/^\circ C$
PSRR	Power-supply sensitivity	See Notes 7 and 8		0.5		mV/V

- NOTES: 1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero and full scale (excluding the effects of zero code and full-scale errors).
2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
4. Zero-scale error temperature coefficient is given by: $ZSETC = [ZSE(T_{max}) - ZSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
5. Full-scale error is the deviation from the ideal full-scale output ($V_{ref} - 1$ LSB) with an output load of 10 k Ω .
6. Full-scale temperature coefficient is given by: $FSETC = [FSE(T_{max}) - FSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
7. Zero-scale error rejection ratio (ZSE-RR) is measured by varying the V_{DD} voltage from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
8. Full-scale error rejection ratio (FSE-RR) is measured by varying the V_{DD} from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

operating characteristics over recommended operating free-air temperature range, $V_{DD} = 5 V \pm 5\%$, $V_{ref} = 2 V$, $\times 1$ gain output range (unless otherwise noted)

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	$C_L = 100$ pF, $R_L = 10$ k Ω		1		V/ μs
Output settling time	To 0.5 LSB, $C_L = 100$ pF, $R_L = 10$ k Ω , See Note 9		10		μs
Large-signal bandwidth	Measured at -3 dB point		100		kHz
Digital crosstalk	CLK = 1-MHz square wave measured at DACA-DACD		-50		dB
Reference feedthrough	See Note 10		-60		dB
Channel-to-channel isolation	See Note 11		-60		dB
Reference input bandwidth	See Note 12		100		kHz

- NOTES: 9. Settling time is the time for the output signal to remain within ± 0.5 LSB of the final measured value for a digital input code change of 00 hex to FF hex or FF hex to 00 hex. For TLC5628C: $V_{DD} = 5 V$, $V_{ref} = 2 V$ and range = $\times 2$. For TLC5628I: $V_{DD} = 3 V$, $V_{ref} = 1.25 V$ and range $\times 2$.
10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex with V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
12. Reference bandwidth is the -3 dB bandwidth with an input at $V_{ref} = 1.25 V$ dc + 2 V_{pp} , with a digital input code of full-scale.



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PARAMETER MEASUREMENT INFORMATION

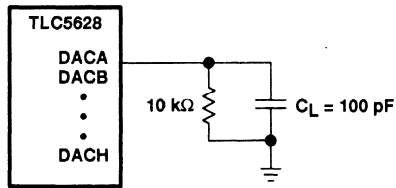


Figure 3. Slew Settling Time and Linearity Measurements

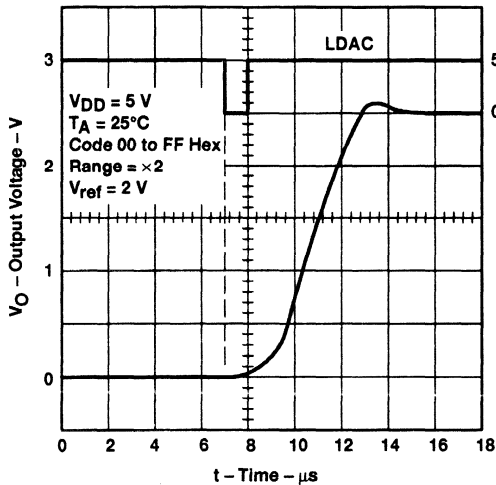


Figure 4. Positive Rise and
Setting Time $V_{DD} = 5 \text{ V}$

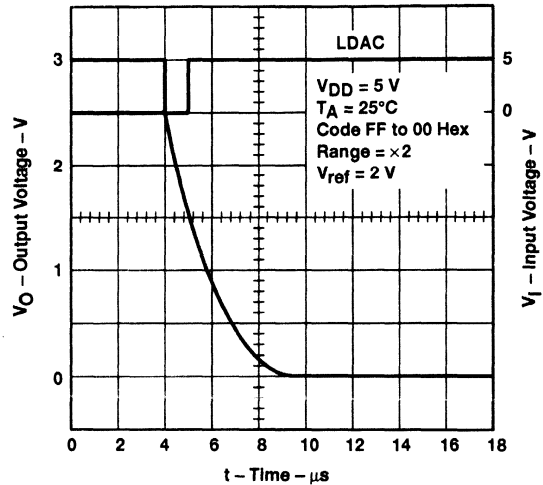
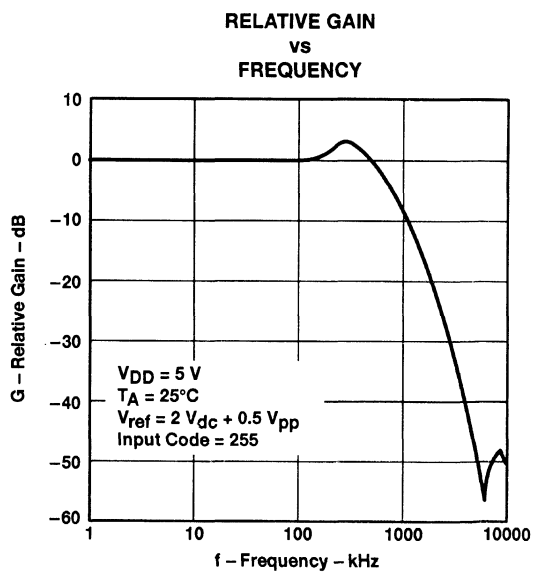
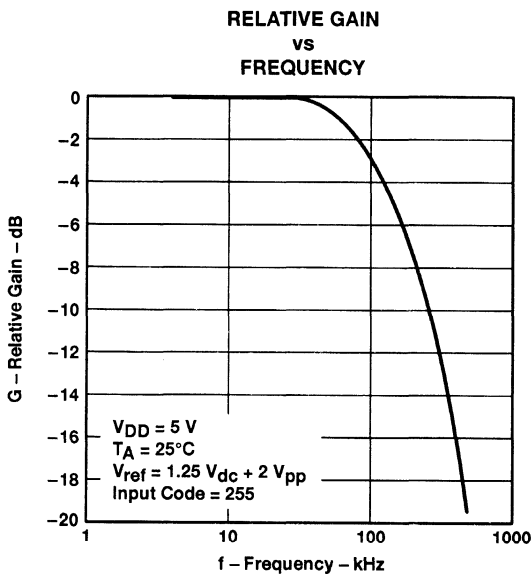
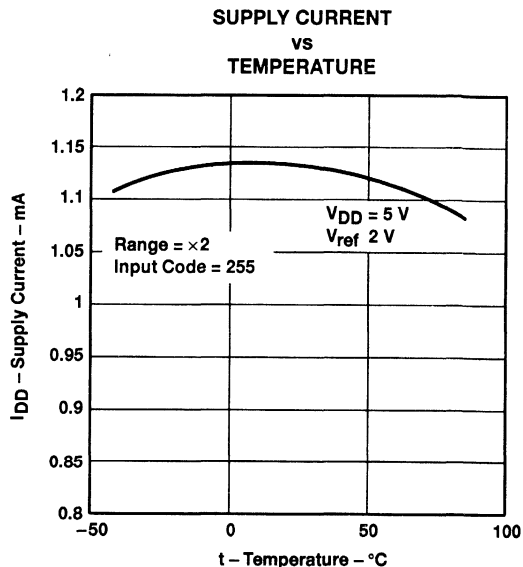
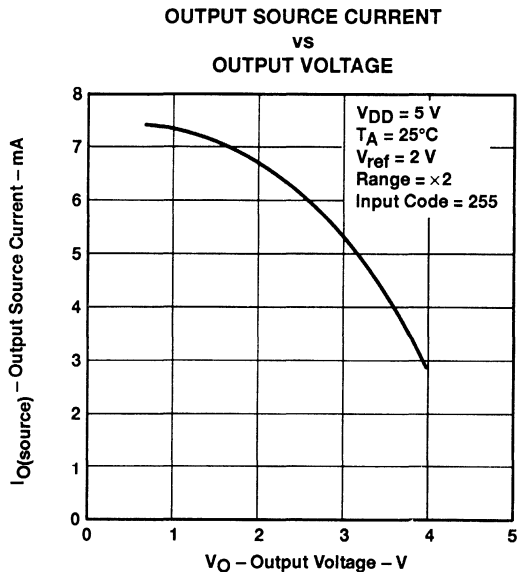


Figure 5. Negative Fall and
Setting Time $V_{DD} = 5 \text{ V}$

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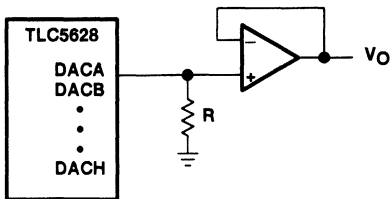
TYPICAL CHARACTERISTICS



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APPLICATION INFORMATION



NOTE A: Resistor $R \geq 10 \text{ k}\Omega$

Figure 10. Output Buffering Schemes

TLC7226C, TLC7226I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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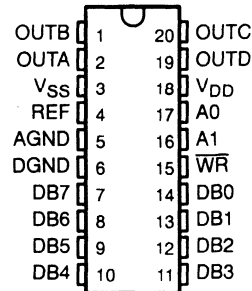
features

- Four 8-Bit D/A Converters
- Microprocessor Compatible
- TTL/CMOS Compatible
- No User Trim Required
- Single Supply Operation Possible
- Simultaneous Update Facility
- CMOS Technology

applications

- Process Control
- Automatic Test Equipment
- Automatic Calibration of Large System Parameters e.g., Gain/Offset

DW OR N PACKAGE
(TOP VIEW)



description

The TLC7226C and TLC7226I consist of four, 8-bit, voltage-output, digital-to-analog converters with output buffer amplifiers and interface logic on a single monolithic chip. No external trims are required to achieve full specified performance for the part.

Separate on-chip latches are provided for each of the four D/A converters. Data is transferred into one of these data latches through a common, 8-bit, TTL/CMOS-compatible (5 V) input port. Control inputs A0 and A1 determine which D/A converter is loaded when WR goes low. The control logic is speed compatible with most 8-bit microprocessors. Since all four D/A converters are fabricated on the same chip at the same time, precise matching and tracking between them is inherent.

Each D/A converter includes an output buffer amplifier capable of sourcing up to 5 mA of output current.

The TLC7226 performance is specified for input reference voltages from 2 V to 12.5 V with dual supplies. The voltage mode configuration of the D/A converters allow the TLC7226 to be operated from a single power supply rail at a reference of 10 V.

The TLC7226 is fabricated in a LinBiCMOS™ process that has been specifically developed to allow high-speed digital logic circuits and precision analog circuits to be integrated on the same chip. The TLC7226 has a common 8-bit data bus with individual D/A converter latches. This provides a versatile control architecture for simple interface to microprocessors. All latch-enable signals are level triggered.

Combining four D/A converters, four operational amplifiers, and interface logic into either a 0.3-inch wide, 20-pin DIP or a small 20-pin small-outline IC (SOIC) allows a dramatic reduction in board space requirements and offers increased reliability in systems using multiple converters. The pinout is aimed at optimizing board layout with all of the analog inputs and outputs at one end of the package and all of the digital inputs at the other.

The TLC7226C is characterized for operation from 0°C to 70°C. The TLC7226I is characterized for operation from –25°C to 85°C.

AVAILABLE OPTIONS

T _A	PACKAGE	
	SMALL OUTLINE (DW)	PLASTIC DIP (N)
0°C to 70°C	TLC7226CDW	TLC7226CN
–25°C to 85°C	TLC7226IDW	TLC7226IN

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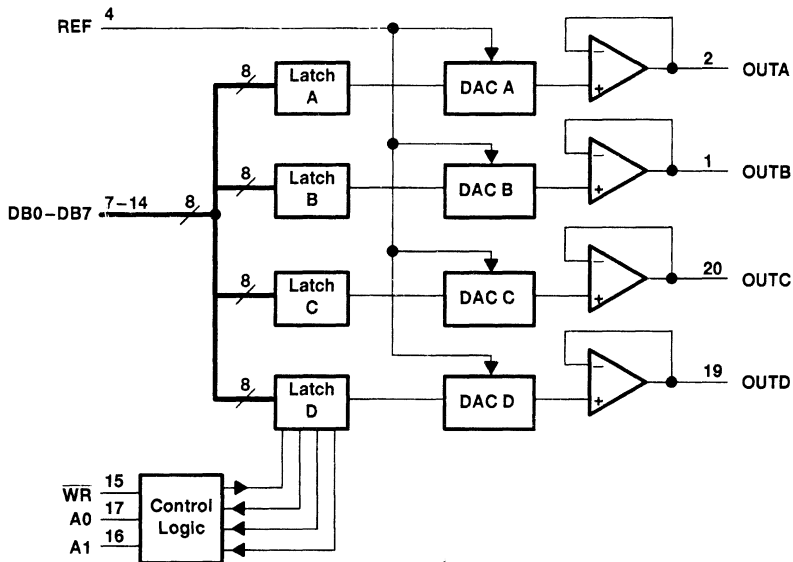
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PRODUCT PREVIEW

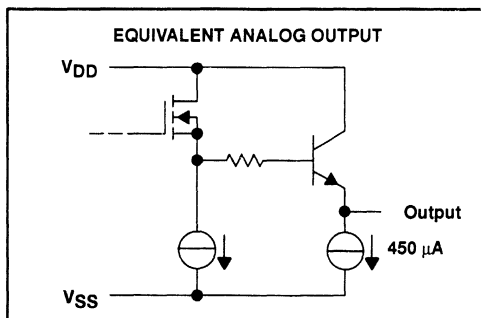
TLC7226C, TLC7226I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



schematic of outputs



PRODUCT PREVIEW

TLC7226C, TLC7226I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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Terminal Functions

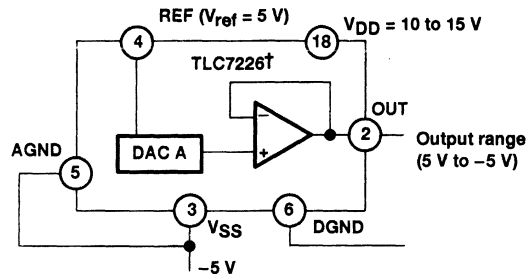
TERMINAL NAME	NO.†	I/O	DESCRIPTION
AGND	5		Analog ground
A0, A1	16, 17	I	DAC select inputs
DGND	6		Digital ground
DB0–DB7	7–14	I	Digital DAC data inputs
OUTA	2	O	DACA output
OUTB	1	O	DACB output
OUTC	20	O	DACC output
OUTD	19	O	DACD output
REF	4	I	Voltage reference input
VDD	18		Positive supply voltage
VSS	3		Negative supply voltage
WR	15	I	Write input selects DAC transparency or latch mode. The selected input latch is transparent when WR is low.

† Terminal numbers shown are for the DW and N packages.

detailed description

AGND bias for direct bipolar output operation

The TLC7226 can be used in bipolar operation without adding more external operational amplifiers as shown in Figure 1 by biasing AGND to VSS. This configuration provides an excellent method for providing a direct bipolar output with no additional components. The transfer values are shown in Table 1.



† Digital inputs omitted for clarity.

Figure 1. AGND Bias for Direct Bipolar Operation

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AGND bias for direct bipolar output operation (continued)

Table 1. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS		ANALOG OUTPUT
MSB	LSB	
1111	1111	$+V_{ref} \left(\frac{127}{128} \right)$
1000	0001	$+V_{ref} \left(\frac{1}{128} \right)$
1000	0000	0 V
0111	1111	$-V_{ref} \left(\frac{1}{128} \right)$
0000	0001	$-V_{ref} \left(\frac{127}{128} \right)$
0000	0000	$-V_{ref} \left(\frac{128}{128} \right) = -V_{ref}$

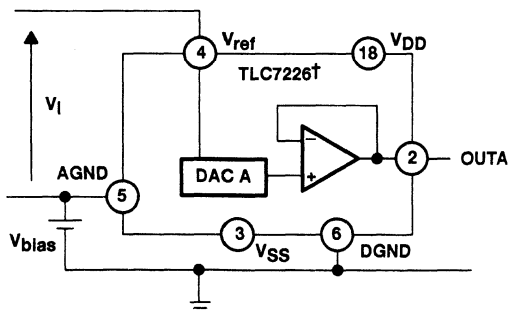
AGND bias for positive output offset

The TLC7226 AGND terminal can be biased above or below the system ground terminal, DGND, to provide an offset zero analog output voltage level. Figure 2 shows a circuit configuration to achieve this for channel A of the TLC7226. The output voltage, V_O , at OUTA can be expressed as:

$$V_O = V_{BIAS} + D_A (V_I)$$

Where D_A is a fractional representation of the digital input word ($0 \leq D \leq 255/256$).

Increasing AGND above system GND reduces the output range. $V_{DD} - V_{ref}$ must be at least 4 V to ensure specified operation. Because the AGND terminal is common to all four DACs, this method biases up the output voltages of all the DACs in the TLC7226. Supply voltages V_{DD} and V_{SS} for the TLC7226 should be referenced to DGND.



† Digital inputs omitted for clarity.

Figure 2. AGND Bias Circuit

PRODUCT PREVIEW

bipolar output operation using external amplifier

Each of the DACs of the TLC7226 can also be individually configured to provide bipolar output operation, using an external amplifier and two resistors per channel. Figure 3 shows a circuit used to implement offset binary coding (bipolar operation) with DAC A of the TLC7226. In this case:

$$V_O = 1 + \frac{R_2}{R_1} \times (D_A \times V_{ref}) - \frac{R_2}{R_1} \times (V_{ref})$$

With $R_1 = R_2$

$$V_O = (2D_A - 1) \times V_{ref}$$

Where D_A is a fractional representation of the digital word in latch A.

Mismatch between R_1 and R_2 causes gain and offset errors. Therefore, these resistors must match and track over temperature. The TLC7226 can be operated with a single supply or from positive and negative supplies.

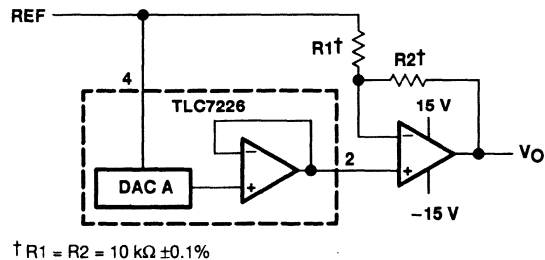


Figure 3. Bipolar Output Circuit

staircase window comparator

In many test systems, it is important to be able to determine whether some parameter lies within defined limits. The staircase window comparator shown in Figure 4 is a circuit that can be used, to measure the V_{OH} and V_{OL} thresholds of a TTL device under test. Upper and lower limits on both V_{OH} and V_{OL} can be programmed using the TLC7226. Each adjacent pair of comparators forms a window of programmable size (see Figure 5). When the test voltage (V_{test}) lines horizontal within a window, then the output for that window is higher. With a reference of 2.56 V applied to the REF input, the minimum window size is 10 mV.

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TLC7226C, TLC7226I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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staircase window comparator (continued)

PRODUCT PREVIEW

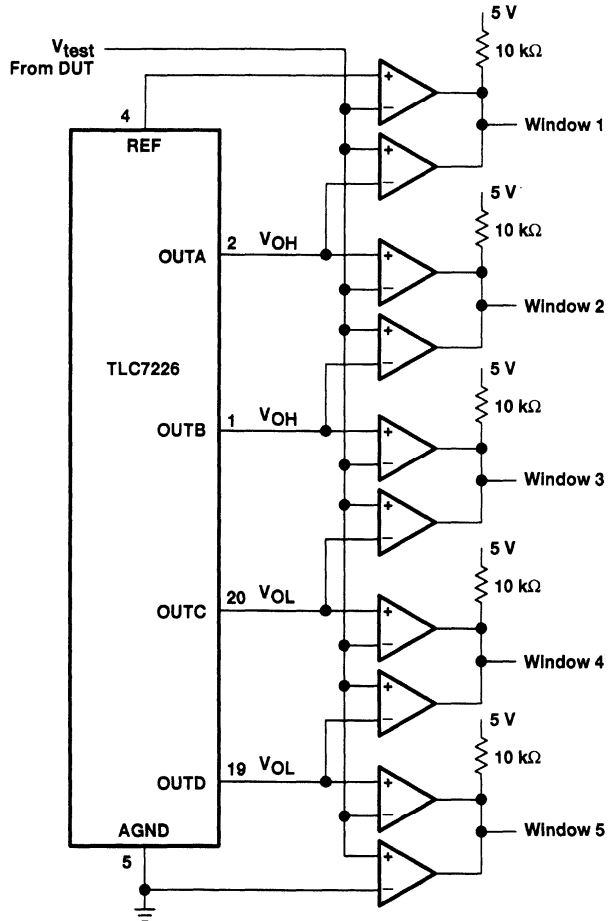


Figure 4. Logic Level Measurement

staircase window comparator (continued)

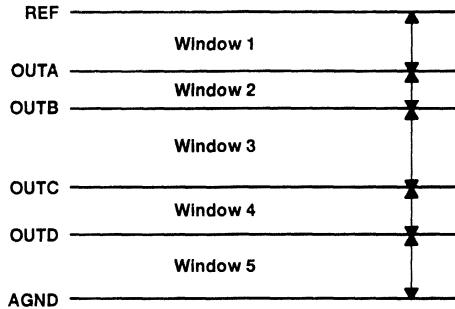


Figure 5. Window Structure

The circuit can easily be adapted to allow for overlapping of windows as shown in Figure 6. When the three outputs from this circuit are decoded, five different nonoverlapping programmable windows can again be defined (see Figure 7).

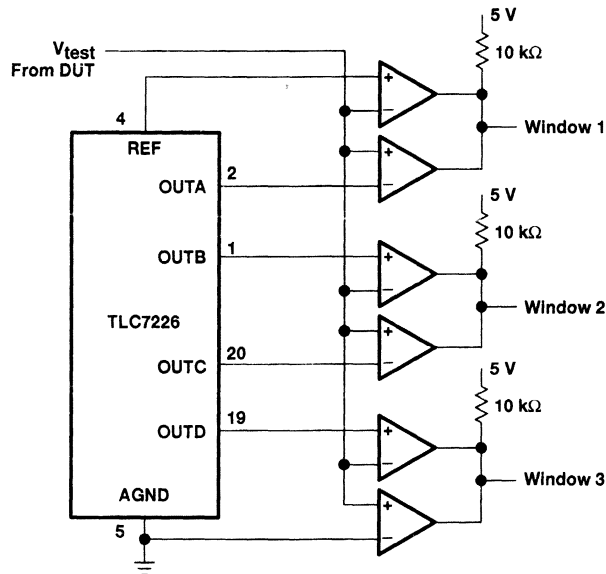


Figure 6. Overlapping Windows

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staircase window comparator (continued)

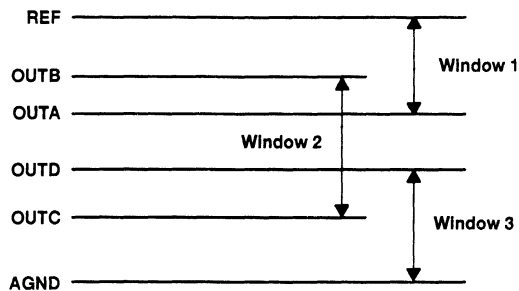


Figure 7. Window Structure

output buffer amplifier

The unity-gain output amplifier is capable of sourcing 5 mA into a 2-k Ω load and can drive a 3300-pF capacitor. The output can be shorted to AGND indefinitely or can be shorted to any voltage between V_{SS} and V_{DD} consistent with the maximum device power dissipation.

multiplying DAC

The TLC7226 can be used as a multiplying DAC if the reference signal is maintained between 2 V and $V_{DD} - 4$ V. When this configuration is used, V_{DD} should be 14.25 V to 15.75 V. A low output impedance buffer should be used so that the input signal is not loaded by the resistor ladder. Figure 8 shows the general schematic.

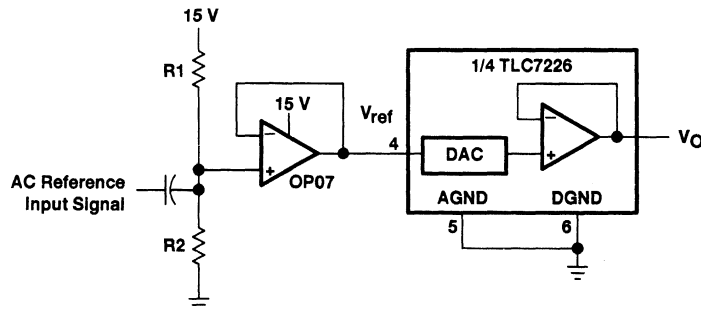


Figure 8. AC Signal Input Scheme

PRODUCT PREVIEW

TLC7226C, TLC7226I

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Interface logic Information

Address lines A0 and A1 select which D/A converter accepts data from the input port. The following function table shows the selection table for the four DACs. Figure 9 shows the input control logic. When the \overline{WR} signal is low, the input latches of the selected DAC are transparent and the output responds to activity on the data bus. The data is latched into the addressed DAC latch on the rising edge of \overline{WR} . While \overline{WR} is high, the analog outputs remain at the value corresponding to the data held in their respective latches.

FUNCTION TABLE

CONTROL INPUTS			OPERATION
\overline{WR}	A1	A2	
H	X	X	No operation Device not selected
L	L	L	DAC A transparent
↑	L	L	DAC A latched
L	L	H	DAC B transparent
↑	L	H	DAC B latched
L	H	L	DAC C transparent
↑	H	L	DAC C latched
L	H	H	DAC D transparent
↑	H	H	DAC D latched

L = low, H = high, X = irrelevant

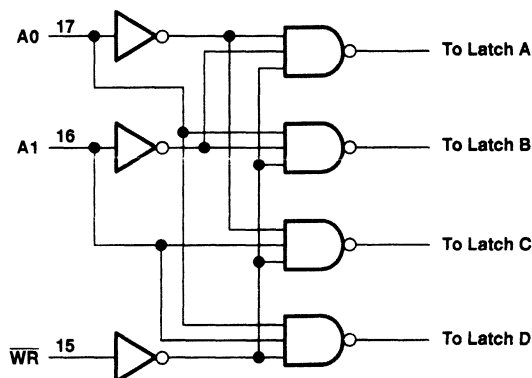


Figure 9. Input Control Logic

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TLC7226C, TLC7226I

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unipolar output operation

The unipolar output operation is the basic mode of operation for each channel of the TLC7226, with the output voltages having the same positive polarity as V_{ref} . The TLC7226 can be operated with a single supply ($V_{SS} = AGND$) or with positive/negative supplies. The voltage at V_{ref} must never be negative with respect to AGND to prevent parasitic transistor turn-on. Connections for the unipolar output operation are shown in Figure 10. Transfer values are shown in Table 2.

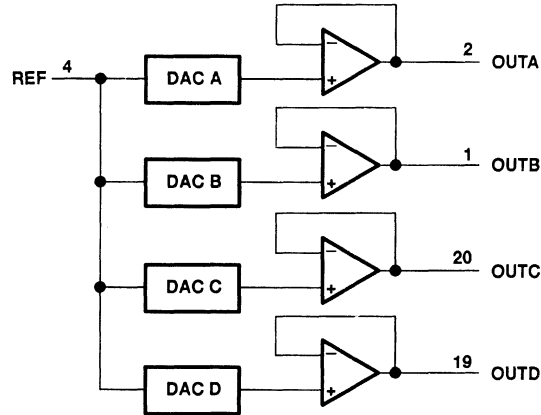


Figure 10. Unipolar Output Circuit

Table 2. Unipolar Code

DAC LATCH CONTENTS		ANALOG OUTPUT
MSB	LSB	
1111	1111	$+ V_{ref} \left(\frac{255}{256} \right)$
1000	0001	$+ V_{ref} \left(\frac{129}{256} \right)$
1000	0000	$+ V_{ref} \left(\frac{128}{256} \right) = + \frac{V_{ref}}{2}$
0111	1111	$+ V_{ref} \left(\frac{127}{256} \right)$
0000	0001	$+ V_{ref} \left(\frac{1}{256} \right)$
0000	0000	0 V

NOTE: $1 \text{ LSB} = (V_{ref} 2^{-8}) = V_{ref} \left(\frac{1}{256} \right)$

PRODUCT PREVIEW

TLC7226C, TLC7226I

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} : to AGND or DGND	-0.3 V to 17 V
to $V_{SS}‡$	-0.3 V to 24 V
Supply voltage range, V_{SS} : to AGND or DGND	-17 V to +0.3 V
Voltage range between AGND and DGND	-17 V to 17 V
Input voltage range, V_I (to DGND)	-0.3 V to $V_{DD} + 0.3$ V
Reference voltage range: V_{ref} (to AGND)	-0.3 V to V_{DD}
V_{ref} (to V_{SS})	-0.3 V to 20 V
Output voltage range, V_O (to AGND) (see Note 1)	V_{SS} to V_{DD}
Continuous total power dissipation at (or below) $T_A = 25^\circ\text{C}$ (see Note 2)	500 mW
Operating free-air temperature range, T_A : C suffix	0°C to 70°C
I suffix	-25°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N packages	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

‡ The V_{SS} terminal is connected to the substrate and must be tied to the most negative supply voltage applied to the device.

NOTES: 1. Output voltages may be shorted to AGND provided that the power dissipation of the package is not exceeded. Typically short circuit current to AGND is 60 mA.

2. For operation above $T_A = 75^\circ\text{C}$ derate linearly at the rate of 2.0 mC/°C.

recommended operating conditions

	MIN	MAX	UNIT	
Supply voltage, V_{DD}	4.5	16.5	V	
Supply voltage, V_{SS}	-0.6	-5.5	V	
High-level input voltage, V_{IH}	$V_{DD} = 4.75$ V	2	V	
	$V_{DD} = 15.75$ V	2		
Low-level input voltage, V_{IL}	$V_{DD} = 4.75$ V	0.8	V	
Reference voltage, V_{ref}	0	$V_{DD} - 4$	V	
Load resistance, R_L	2		k Ω	
Setup time, address valid before \overline{WR} , $t_{su}(AW)$	0		ns	
Setup time, data valid before \overline{WR} , $t_{su}(DW)$	$V_{DD} = 4.75$ V to 5.25 V	70	ns	
	$V_{DD} = 4.75$ V to 5.25 V	180		
Hold time, address valid before \overline{WR} , $t_h(AW)$	$V_{DD} = 4.75$ V to 5.25 V	10	ns	
	$V_{DD} = 4.75$ V to 5.25 V	20		
Hold time, data valid before \overline{WR} , $t_h(DW)$	$V_{DD} = 4.75$ V to 5.25 V	0	ns	
	$V_{DD} = 4.75$ V to 5.25 V	20		
Pulse duration, \overline{WR} low, t_w	$V_{DD} = 4.75$ V to 5.25 V	50	ns	
	$V_{DD} = 4.75$ V to 5.25 V	180		
Operating free-air temperature, T_A	C suffix	0	70	°C
	I suffix	-25	85	°C

PRODUCT PREVIEW



TLC7226C, TLC7226I

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electrical characteristics over recommended operating free-air temperature range

dual power supply over recommended supply and reference voltage ranges, AGND = DGND = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_I	Input current, digital	$V_I = 0\text{ V or }V_{DD}$			+1	μA
I_{DD}	Supply current	$V_I = V_{IL}\text{ or }V_{IH}$, No load		6	12	mA
I_{SS}	Supply current	$V_I = V_{IL}\text{ or }V_{IH}$, No load		4	10	mA
$r_{i(\text{ref})}$	Reference input resistance		2	4		k Ω
	Power supply sensitivity	$\Delta V_{DD} = \pm 5\%$			0.01	%/%
C_i	Input capacitance	REF input	All 0's loaded	65		pF
			All 1's loaded		300	
		Digital inputs			8	

single power supply, $V_{DD} = 14.25\text{ V to }15.75\text{ V}$, $V_{SS} = \text{AGND} = \text{DGND} = 0\text{ V}$, $V_{\text{ref}} = 10\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT	
I_I	Input current, digital	$V_I = 0\text{ V or }V_{DD}$		± 1	μA	
I_{DD}	Supply current	$V_I = V_{IL}\text{ or }V_{IH}$, No load		13	mA	
	Power supply sensitivity	$\Delta V_{DD} = \pm 5\%$		0.01	%/%	
C_i	Input capacitance	REF input	All 0's loaded	65		pF
			All 1's loaded		300	
		Digital inputs			8	

single or dual power supplies, $V_{DD} = 4.75\text{ V to }5.25\text{ V}$, $V_{SS} = \text{AGND} = \text{DGND} = 0\text{ V or }V_{SS} = -5\text{ V}$, $V_{\text{ref}} = 1.25\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT	
I_I	Input current, digital	$V_I = 0\text{ V or }V_{DD}$		± 1	μA	
I_{DD}	Supply current	$V_I = V_{IL}\text{ or }V_{IH}$, No load		12	mA	
r_i	Input resistance		2		k Ω	
	Power supply sensitivity	$\Delta V_{DD} = \pm 5\%$		0.01	%/%	
C_i	Input capacitance	REF input	All 0's loaded	65		pF
			All 1's loaded		300	
		Digital inputs			8	

PRODUCT PREVIEW



TLC7226C, TLC7226I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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operating characteristics over recommended operating free-air temperature range

dual power supply over recommended supply and reference voltage ranges, AGND = DGND = 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Slew rate			2.5			V/μs
Settling time to 1/2 LSB	Positive full scale	V _{ref} = 10 V			5	μs
	Negative full scale				7	
Resolution				8		Bits
Total unadjusted error		V _{DD} = 15 V ±5%, V _{ref} = 10 V			±2	LSB
Linearity error	Differential/integral				±1	LSB
Full-scale error					±1.5	LSB
Temperature coefficient of gain	Full scale	V _{DD} = 14 V to 16.5 V, V _{ref} = 10 V			±20	ppm/°C
	Zero-code error				±50	μV/°C
Zero-code error					±30	mV
Digital crosstalk glitch impulse area		V _{ref} = 0 V			50	nV•s

single power supply, V_{DD} = 14.25 V to 15.75 V, V_{SS} = AGND = DGND = 0 V, V_{ref} = 10 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Slew rate			2			V/μs
Settling time to 1/2 LSB	Positive full scale				5	μs
	Negative full scale				20	
Resolution				8		Bits
Total unadjusted error					±2	LSB
Full-scale error					±1.5	LSB
Temperature coefficient of gain	Full scale	V _{DD} = 14 V to 16.5 V, V _{ref} = 10 V			±20	ppm/°C
	Zero-code error				±50	μV/°C
Linearity error	Differential				±1	LSB
Digital crosstalk glitch impulse area					50	nV•s

single or dual power supplies, V_{DD} = 4.75 V to 5.25 V, V_{SS} = AGND = DGND or V_{SS} = -5 V, V_{ref} = 1.25 V (unless otherwise noted)

PARAMETER		MIN	MAX	UNIT
Linearity error	Differential		±1	LSB
Full-scale error			±4	LSB
Zero-code error			±30	mV

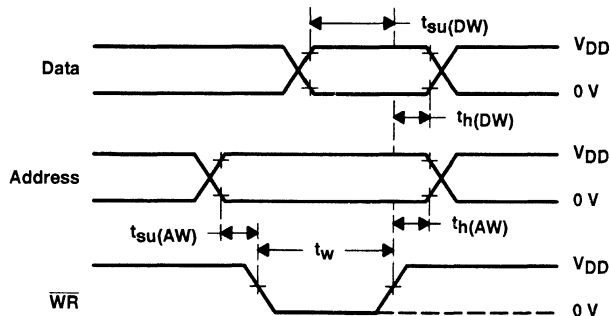
PRODUCT PREVIEW



TLC7226C, TLC7226I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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PARAMETER MEASUREMENT INFORMATION



- NOTES: A. $t_r = t_f = 20$ ns over V_{DD} range.
 B. The timing measurement reference level is equal to $V_{IH} + V_{IL}$ divided by 2.
 C. The selected input latch is transparent while \overline{WR} is low. Invalid data during this time can cause erroneous outputs.

Figure 11. Write-Cycle Voltage Waveforms

PRODUCT PREVIEW

TYPICAL CHARACTERISTICS

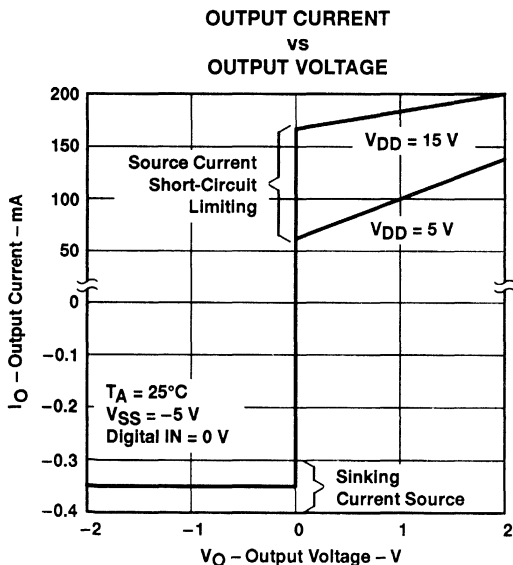


Figure 12

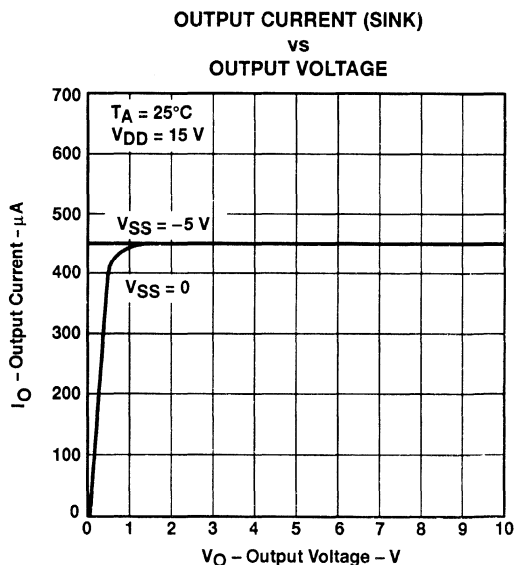


Figure 13

TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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- Easily Interfaced to Microprocessors
- On-Chip Data Latches
- Monotonic Over the Entire A/D Conversion Range
- Segmented High-Order Bits Ensure Low-Glitch Output
- Interchangeable With Analog Devices AD7524, PMI PM-7524, and Micro Power Systems MP7524
- Fast Control Signaling for Digital Signal-Processor Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 Bits
Linearity error	1/2 LSB Max
Power dissipation at $V_{DD} = 5\text{ V}$	5 mW Max
Setting time	100 ns Max
Propagation delay time	80 ns Max

description

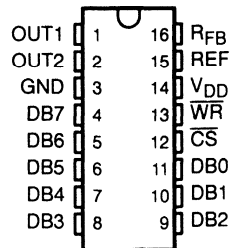
The TLC7524C, TLC7524E, and TLC7524I are CMOS, 8-bit, digital-to-analog converters (DACs) designed for easy interface to most popular microprocessors.

The devices are 8-bit, multiplying DACs with input latches and load cycles similar to the write cycles of a random access memory. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, which produce the highest glitch impulse. The devices provide accuracy to 1/2 LSB without the need for thin-film resistors or laser trimming, while dissipating less than 5 mW typically.

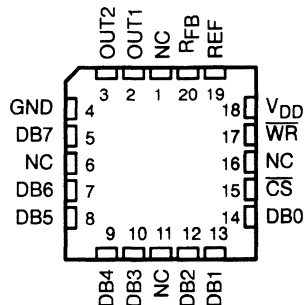
Featuring operation from a 5-V to 15-V single supply, these devices interface easily to most microprocessor buses or output ports. The 2- or 4-quadrant multiplying makes these devices an ideal choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7524C is characterized for operation from 0°C to 70°C. The TLC7524I is characterized for operation from -25°C to 85°C. The TLC7524E is characterized for operation from -40°C to 85°C.

D OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



NC—No internal connection

AVAILABLE OPTIONS

T _A	PACKAGE		
	SMALL OUTLINE PLASTIC DIP (D)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC7524CD	TLC7524CFN	TLC7524CN
-25°C to 85°C	TLC7524ID	TLC7524IFN	TLC7524IN
-40°C to 85°C	TLC7524ED	TLC7524EFN	TLC7524EN

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



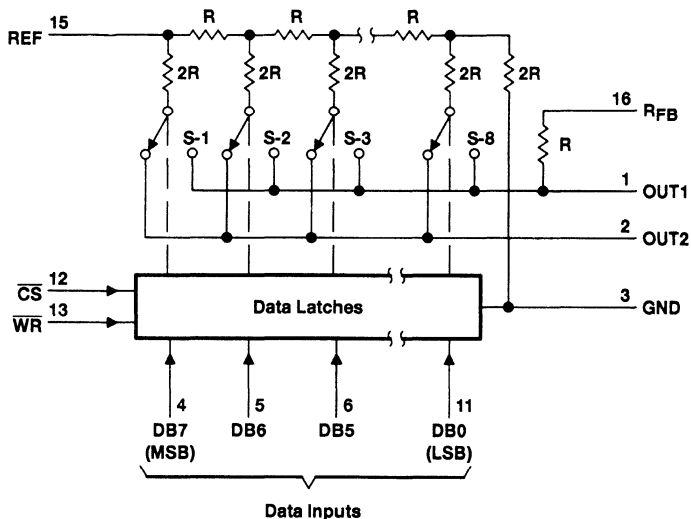
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TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



Terminal numbers shown are for the D or N package.

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)

Supply voltage range, V_{DD}	-0.3 V to 16.5 V
Digital input voltage range, V_I	-0.3 V to $V_{DD} + 0.3$ V
Reference voltage, V_{ref}	± 25 V
Peak digital input current, I_I	10 μ A
Operating free-air temperature range, T_A :	TLC7524C	0°C to 70°C
	TLC7524I	-25°C to 85°C
	TLC7524E	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds, T_C : FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D or N package	260°C

TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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recommended operating conditions

	V _{DD} = 5 V			V _{DD} = 15 V			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V _{DD}	4.75	5	5.25	14.5	15	15.5	V
Reference voltage, V _{ref}	±10			±10			V
High-level input voltage, V _{IH}	2.4						V
Low-level input voltage, V _{IL}				0.8			V
CS setup time, t _{su} (CS)	40			40			ns
CS hold time t _h (CS)	0			0			ns
Data bus input setup time t _{su} (D)	25			25			ns
Data bus input hold time t _h (D)	10			10			ns
Pulse duration, WR low, t _w (WR)	40			40			ns
Operating free-air temperature, T _A	TLC7524C		0	70	0	70	°C
	TLC7524I		-25	85	-25	85	
	TLC7524E		-40	85	-40	85	

electrical characteristics over recommended operating free-air temperature range, V_{ref} = ±10 V, OUT1 and OUT2 at GND (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V _{DD} = 5 V			V _{DD} = 15 V			UNIT
			MIN	TYP	MAX	MIN	TYP	MAX	
I _{IH}	High-level input current	V _I = V _{DD}	10			10			μA
I _{IL}	Low-level input current	V _I = 0	-10			-10			μA
I _{lkg}	Output leakage current	OUT1 DB0–DB7 at 0 V, \overline{WR} , \overline{CS} at 0 V, V _{ref} = ±10 V	±400			±200			nA
		OUT2 DB0–DB7 at V _{DD} , \overline{WR} , \overline{CS} at 0 V, V _{ref} = ±10 V	±400			±200			
I _{DD}	Supply current	Quiescent	1			2			mA
		Standby	500			500			μA
kSVS	Supply voltage sensitivity, Δgain/ΔV _{DD}	ΔV _{DD} = ±10%	0.01	0.16	0.005	0.04	%FSR/%		
C _i	Input capacitance, DB0–DB7, \overline{WR} , \overline{CS}	V _I = 0	5			5			pF
C _o	Output capacitance	OUT1	30			30			pF
		OUT2	120			120			
		OUT1	120			120			
		OUT2	30			30			
Reference input impedance (REF to GND)			5	20	5	20	kΩ		

TLC7524C, TLC7524E, TLC7524I

8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

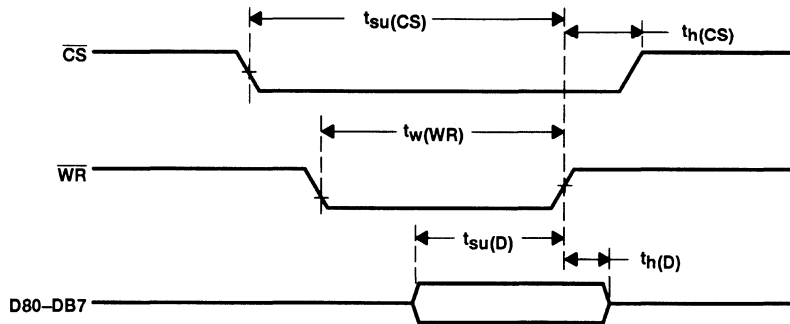
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operating characteristics over recommended operating free-air temperature range, $V_{ref} = \pm 10$ V, OUT1 and OUT2 at GND (unless otherwise noted)

PARAMETER	TEST CONDITIONS	$V_{DD} = 5$ V			$V_{DD} = 15$ V			UNIT
		MIN	TYP	MAX	MIN	TYP	MAX	
Linearity error				± 0.5			± 0.5	LSB
Gain error	See Note 1			± 2.5			± 2.5	LSB
Settling time (to 1/2 LSB)	See Note 2			100			100	ns
Propagation delay from digital input to 90% of final analog output current	See Note 2			80			80	ns
Feedthrough at OUT1 or OUT2	$V_{ref} = \pm 10$ V (100-kHz sinewave) \overline{WR} and \overline{CS} at 0 V, DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V			0.5			0.5	%FSR
Temperature coefficient of gain	$T_A = 25^\circ\text{C}$ to MAX			± 0.004			± 0.001	%FSR/ $^\circ\text{C}$

NOTES: 1. Gain error is measured using the internal feedback resistor. Nominal full scale range (FSR) = $V_{ref} - 1$ LSB.
2. OUT1 load = 100 Ω , $C_{ext} = 13$ pF, \overline{WR} at 0 V, \overline{CS} at 0 V, DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.

operating sequence



TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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APPLICATION INFORMATION

voltage-mode operation

It is possible to operate the current-multiplying DAC in these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 1 is an example of a current-multiplying DAC, which is operated in voltage mode.

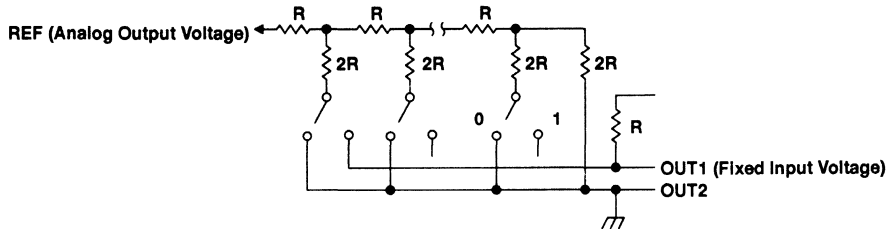


Figure 1. Voltage Mode Operation

The relationship between the fixed-input voltage and the analog-output voltage is given by the following equation:

$$V_O = V_I (D/256)$$

where

- V_O = analog output voltage
- V_I = fixed input voltage
- D = digital input code converted to decimal

In voltage-mode operation, these devices meet the following specification:

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Linearity error at REF	$V_{DD} = 5 \text{ V}$, $\text{OUT1} = 2.5 \text{ V}$, OUT2 at GND, $T_A = 25^\circ\text{C}$		1	LSB

TLC7524C, TLC7524E, TLC7524I

8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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PRINCIPLES OF OPERATION

The TLC7524C, TLC7524E, and TLC7524I are 8-bit multiplying DACs consisting of an inverted R-2R ladder, analog switches, and data input latches. Binary-weighted currents are switched between the OUT1 and OUT2 bus lines, thus maintaining a constant current in each ladder leg independent of the switch state. The high-order bits are decoded. These decoded bits, through a modification in the R-2R ladder, control three equally-weighted current sources. Most applications only require the addition of an external operational amplifier and a voltage reference.

The equivalent circuit for all digital inputs low is seen in Figure 2. With all digital inputs low, the entire reference current, I_{ref} , is switched to OUT2. The current source $I/256$ represents the constant current flowing through the termination resistor of the R-2R ladder, while the current source I_{lkg} represents leakage currents to the substrate. The capacitances appearing at OUT1 and OUT2 are dependent upon the digital input code. With all digital inputs high, the off-state switch capacitance (30 pF maximum) appears at OUT2 and the on-state switch capacitance (120 pF maximum) appears at OUT1. With all digital inputs low, the situation is reversed as shown in Figure 2. Analysis of the circuit for all digital inputs high is similar to Figure 2; however, in this case, I_{ref} would be switched to OUT1.

The DAC on these devices interfaces to a microprocessor through the data bus and the \overline{CS} and \overline{WR} control signals. When \overline{CS} and \overline{WR} are both low, analog output on these devices responds to the data activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the \overline{CS} signal or \overline{WR} signal goes high, the data on the DB0–DB7 inputs are latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled regardless of the state of the \overline{WR} signal.

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant or 4-quadrant multiplication are shown in Figures 3 and 4. Tables 1 and 2 summarize input coding for unipolar and bipolar operation respectively.

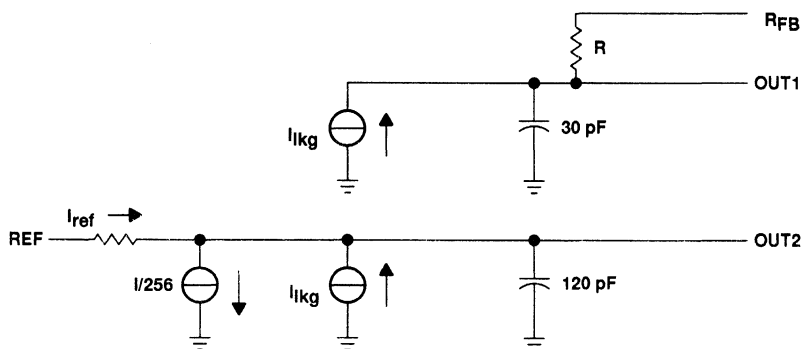


Figure 2. TLC7524 Equivalent Circuit With All Digital Inputs Low

TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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PRINCIPLES OF OPERATION

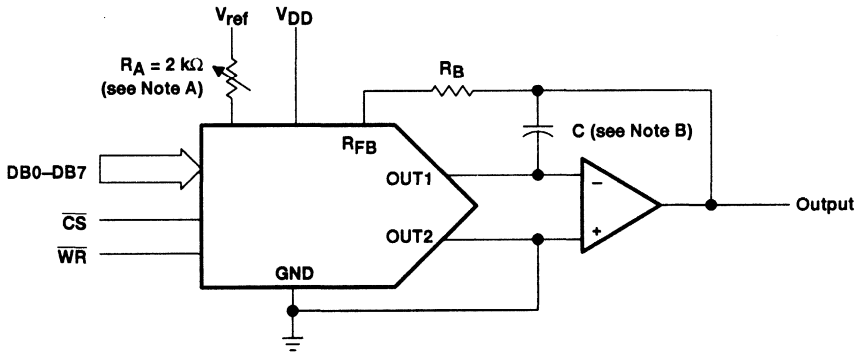


Figure 3. Unipolar Operation (2-Quadrant Multiplication)

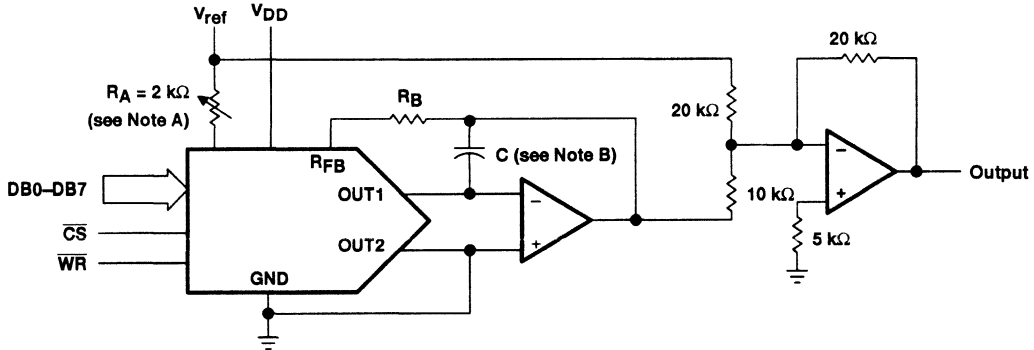


Figure 4. Bipolar Operation (4-Quadrant Operation)

- NOTES: A. R_A and R_B used only if gain adjustment is required.
B. C phase compensation (10-15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.

Table 1. Unipolar Binary Code

DIGITAL INPUT (see Note 3)		ANALOG OUTPUT
MSB	LSB	
1	11111111	$-V_{ref} (255/256)$
1	00000001	$-V_{ref} (129/256)$
1	00000000	$-V_{ref} (128/256) = -V_{ref}/2$
0	11111111	$-V_{ref} (127/256)$
0	00000001	$-V_{ref} (1/256)$
0	00000000	0

Table 2. Bipolar (Offset Binary) Code

DIGITAL INPUT (see Note 4)		ANALOG OUTPUT
MSB	LSB	
1	11111111	$V_{ref} (127/128)$
1	00000001	$V_{ref} (1/128)$
1	00000000	0
0	11111111	$-V_{ref} (1/128)$
0	00000001	$-V_{ref} (127/128)$
0	00000000	$-V_{ref}$

- NOTES: 3. $LSB = 1/256 (V_{ref})$
4. $LSB = 1/128 (V_{ref})$

TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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PRINCIPLES OF OPERATION

microprocessor interfaces

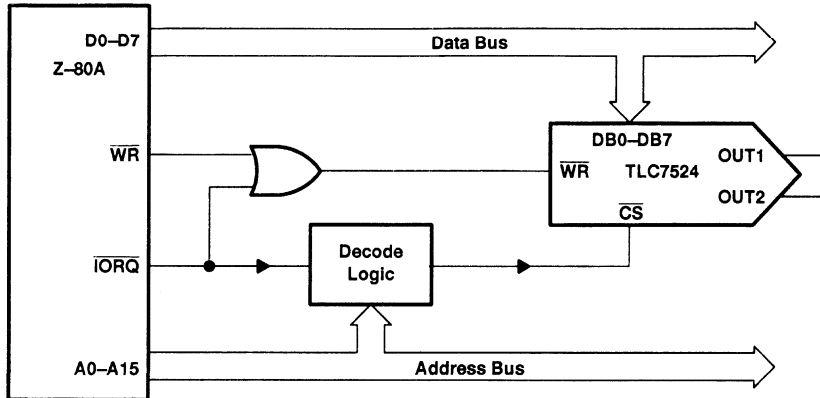


Figure 5. TLC7524 – Z-80A Interface

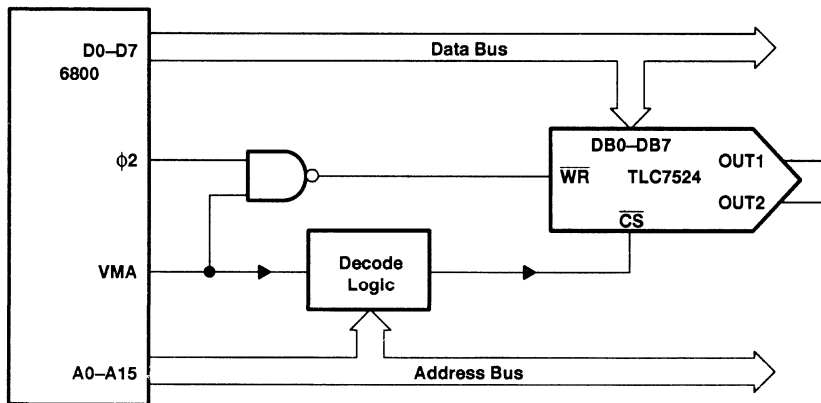


Figure 6. TLC7524 – 6800 Interface

TLC7524C, TLC7524E, TLC7524I 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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microprocessor interfaces (continued)

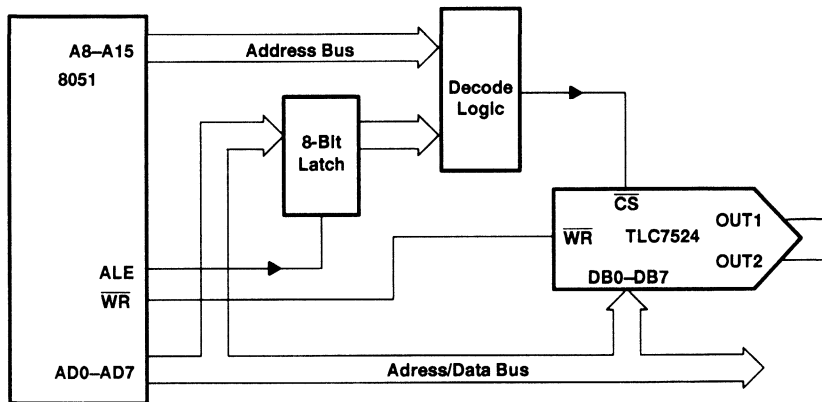


Figure 7. TLC7524 - 8051 Interface

TLC7528C, TLC7528E, TLC7528I DUAL 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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- Easily Interfaced to Microprocessors
- On-Chip Data Latches
- Monotonic Over the Entire A/D Conversion Range
- Interchangeable With Analog Devices AD7528 and PMI PM-7528
- Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320
- Voltage-Mode Operation
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 bits
Linearity Error	1/2 LSB
Power Dissipation at $V_{DD} = 5\text{ V}$	20 mW
Settling Time at $V_{DD} = 5\text{ V}$	100 ns
Propagation Delay Time at $V_{DD} = 5\text{ V}$	80 ns

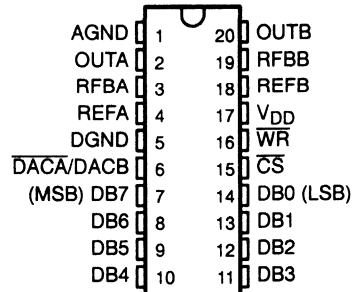
description

The TLC7528C, TLC7528E, and TLC7528I are dual, 8-bit, digital-to-analog converters designed with separate on-chip data latches and feature exceptionally close DAC-to-DAC matching. Data is transferred to either of the two DAC data latches through a common, 8-bit, input port. Control input $\overline{\text{DACA/DACB}}$ determines which DAC is to be loaded. The load cycle of these devices is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

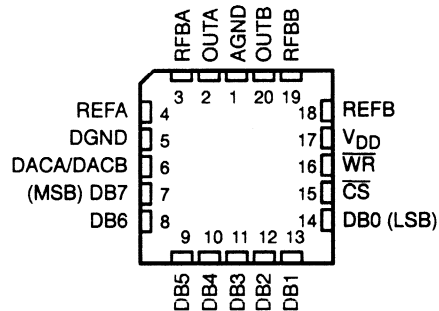
These devices operate from a 5-V to 15-V power supply and dissipates less than 15 mW (typical). The 2- or 4-quadrant multiplying makes these devices a sound choice for many microprocessor-controlled gain-setting and signal-control applications. It can be operated in voltage mode, which produces a voltage output rather than a current output. Refer to the typical application information in this data sheet.

The TLC7528C is characterized for operation from 0°C to 70°C. The TLC7528I is characterized for operation from -25°C to 85°C. The TLC7528E is characterized for operation from -40°C to 85°C.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



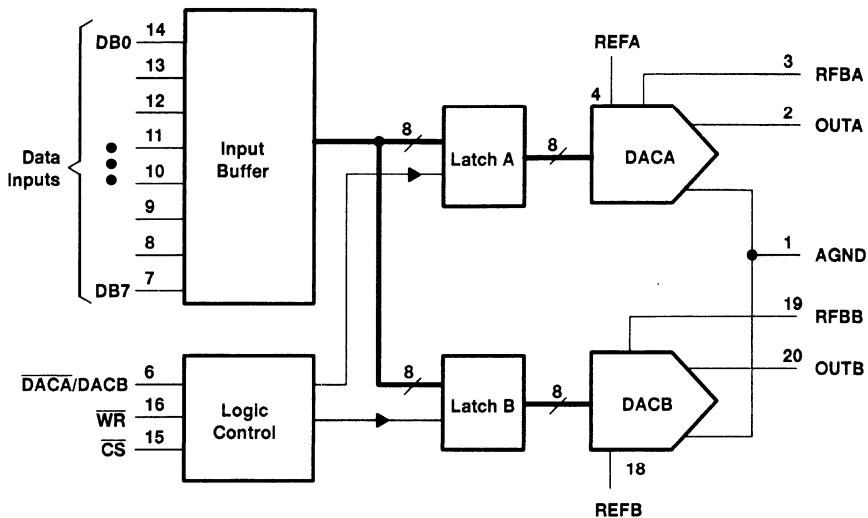
AVAILABLE OPTIONS

T_A	PACKAGE		
	SMALL OUTLINE (DW)	CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC7528CDW	TLC7528CFN	TLC7528CN
-25°C to 85°C	TLC7528IDW	TLC7528IFN	TLC7528IN
-40°C to 85°C	TLC7528EDW	TLC7528EFN	TLC7528EN

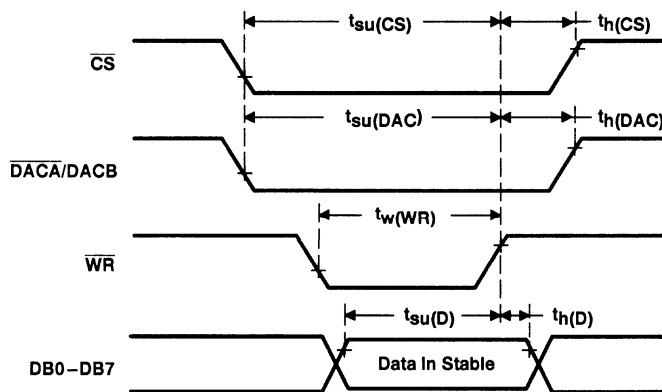
TLC7528C, TLC7528E, TLC7528I
DUAL 8-BIT MULTIPLYING
DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



operating sequence



TLC7528C, TLC7528E, TLC7528I
DUAL 8-BIT MULTIPLYING
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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} (to AGND or DGND)	–0.3 V to 16.5 V
Voltage between AGND and DGND	$\pm V_{DD}$
Input voltage range, V_I (to DGND)	–0.3 V to $V_{DD} + 0.3$
Reference voltage, V_{refA} or V_{refB} (to AGND)	± 25 V
Feedback voltage V_{RFBA} or V_{RFBB} (to AGND)	± 25 V
Output voltage, V_{OA} or V_{OB} (to AGND)	± 25 V
Peak input current	10 μ A
Operating free-air temperature range, T_A : TLC7528C	0°C to 70°C
TLC7528I	–25°C to 85°C
TLC7528E	–40°C to 85°C
Storage temperature range, T_{stg}	–65°C to 150°C
Case temperature for 10 seconds, T_C : FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	$V_{DD} = 4.75$ V to 5.25 V			$V_{DD} = 14.5$ V to 15.5 V			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Reference voltage, V_{refA} or V_{refB}	± 10			± 10			V
High-level input voltage, V_{IH}	2.4			13.5			V
Low-level input voltage, V_{IL}	0.8			1.5			V
\overline{CS} setup time, $t_{su}(CS)$	50			50			ns
\overline{CS} hold time, $t_h(CS)$	0			0			ns
DAC select setup time, $t_{su}(DAC)$	50			50			ns
DAC select hold time, $t_h(DAC)$	10			10			ns
Data bus input setup time $t_{su}(D)$	25			25			ns
Data bus input hold time $t_h(D)$	10			10			ns
Pulse duration, \overline{WR} low, $t_w(WR)$	50			50			ns
Operating free-air temperature, T_A	TLC7628C	0 70		0 70		°C	
	TLC7628I	–25 85		–25 85			
	TLC7628E	–40 85		–40 85			



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electrical characteristics over recommended operating free-air temperature range,
 $V_{refA} = V_{refB} = 10\text{ V}$, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$V_{DD} = 5\text{ V}$			$V_{DD} = 15\text{ V}$			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
I_{IH}	High-level input current	$V_I = V_{DD}$			10			10	μA
I_{IL}	Low-level input current	$V_I = 0$	5	12	-10	5	12	-10	μA
Reference input impedance REFA or REFB to AGND					20			20	$\text{k}\Omega$
I_{lkg}	Output Leakage Current	OUTA	DAC data latch loaded with 00000000, $V_{refA} = \pm 10\text{ V}$			± 400			nA
		OUTB	DAC data latch loaded with 00000000, $V_{refB} = \pm 10\text{ V}$			± 400			
Input resistance match (REFA to REFB)					$\pm 1\%$			$\pm 1\%$	
DC supply sensitivity, $\Delta\text{gain}/\Delta V_{DD}$		$\Delta V_{DD} = \pm 10\%$			0.04			0.02	%/%
I_{DD}	Supply current (quiescent)	All digital inputs at V_{IHmin} or V_{ILmax}			2			2	mA
I_{DD}	Supply current (standby)	All digital inputs at 0 V or V_{DD}			0.5			0.5	mA
C_i	Input capacitance	DB0–DB7			10			10	pF
		\overline{WR} , \overline{CS} , DACA/DACB			15			15	pF
C_o	Output capacitance (OUTA, OUTB)	DAC data latches loaded with 00000000			50			50	pF
		DAC data latches loaded with 11111111			120			120	

† All typical values are at $T_A = 25^\circ\text{C}$.



TLC7528C, TLC7528E, TLC7528I
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operating characteristic over recommended operating free-air temperature range,
 $V_{refA} = V_{refB} = 10\text{ V}$, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	$V_{DD} = 5\text{ V}$		$V_{DD} = 15\text{ V}$		UNIT
			MIN	TYP	MAX	MIN	
Linearity error			$\pm 1/2$		$\pm 1/2$		LSB
Settling time (to 1/2 LSB)		See Note 1	100		100		ns
Gain error		See Note 2	2.5		2.5		LSB
AC feedthrough	REFA to OUTA	See Note 3	-65		-65		dB
	REFB to OUTB		-65		-65		
Temperature coefficient of gain		See Note 4	0.007		0.0035		%FSR/°C
Propagation delay (from digital input to 90% of final analog output current)		See Note 5	80		80		ns
Channel-to-channel isolation	REFA to OUTB	See Note 6	77		77		dB
	REFB to OUTA	See Note 7	77		77		
Digital-to-analog glitch impulse area		Measured for code transition from 00000000 to 11111111, $T_A = 25^\circ\text{C}$	160		440		nV•s
Digital crosstalk		Measured for code transition from 00000000 to 11111111, $T_A = 25^\circ\text{C}$	30		60		nV•s
Harmonic distortion		$V_i = 6\text{ V}$, $f = 1\text{ kHz}$, $T_A = 25^\circ\text{C}$	-85		-85		dB

- NOTES: 1. OUTA, OUTB load = 100 Ω , $C_{ext} = 13\text{ pF}$; \overline{WR} and \overline{CS} at 0 V; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
 2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) = $V_{ref} - 1\text{ LSB}$.
 3. $V_{ref} = 20\text{ V}$ peak-to-peak, 100-kHz sine wave; DAC data latches loaded with 00000000.
 4. Temperature coefficient of gain measured from 0°C to 25°C or from 25°C to 70°C.
 5. $V_{refA} = V_{refB} = 10\text{ V}$; OUTA/OUTB load = 100 Ω , $C_{ext} = 13\text{ pF}$; \overline{WR} and \overline{CS} at 0 V; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.
 6. Both DAC latches loaded with 11111111; $V_{refA} = 20\text{ V}$ peak-to-peak, 100-kHz sine wave; $V_{refB} = 0$; $T_A = 25^\circ\text{C}$.
 7. Both DAC latches loaded with 11111111; $V_{refB} = 20\text{ V}$ peak-to-peak, 100-kHz sine wave; $V_{refA} = 0$; $T_A = 25^\circ\text{C}$.

PRINCIPLES OF OPERATION

These devices contain two identical, 8-bit-multiplying D/A converters, DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified D/A circuit for DACA with all digital inputs low is shown in Figure 1.

Figure 2 shows the DACA equivalent circuit. A similar equivalent circuit can be drawn for DACB. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the entire reference current flows to OUTA. A small leakage current (I_{lkg}) flows across internal junctions, and as with most semiconductor devices, doubles every 10°C. C_o is due to the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of C_o is 50 pF to 120 pF maximum. The equivalent output resistance (r_o) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

These devices interface to a microprocessor through the data bus, \overline{CS} , \overline{WR} , and $\overline{DACA/DACB}$ control signals. When \overline{CS} and \overline{WR} are both low, the TLC7528 analog output, specified by the $\overline{DACA/DACB}$ control line, responds to the activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the \overline{CS} signal or \overline{WR} signal goes high, the data on the DB0–DB7 inputs is latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled regardless of the state of the \overline{WR} signal.

TLC7528C, TLC7528E, TLC7528I
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DIGITAL-TO-ANALOG CONVERTERS

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PRINCIPLES OF OPERATION

The digital inputs of these devices provide TTL compatibility when operated from a supply voltage of 5 V. These devices can operate with any supply voltage in the range from 5 V to 15 V; however, input logic levels are not TTL compatible above 5 V.

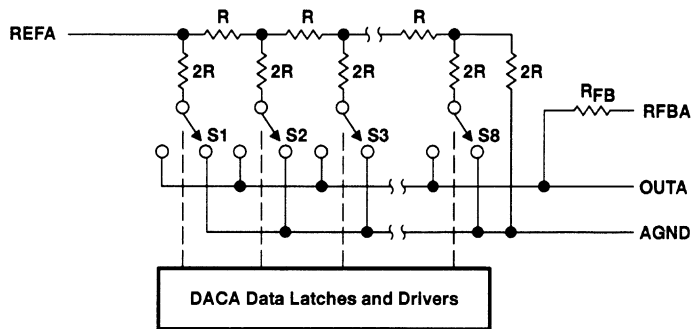


Figure 1. Simplified Functional Circuit for DACA

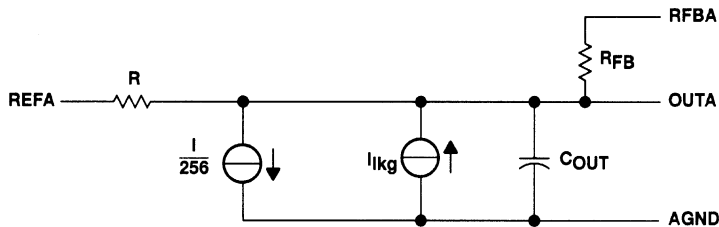


Figure 2. TLC7528 Equivalent Circuit, DACA Latch Loaded With 11111111

MODE SELECTION TABLE

DACA/DACB	CS	WR	DACA	DACB
L	L	L	Write	Hold
H	L	L	Hold	Write
X	H	X	Hold	Hold
X	X	H	Hold	Hold

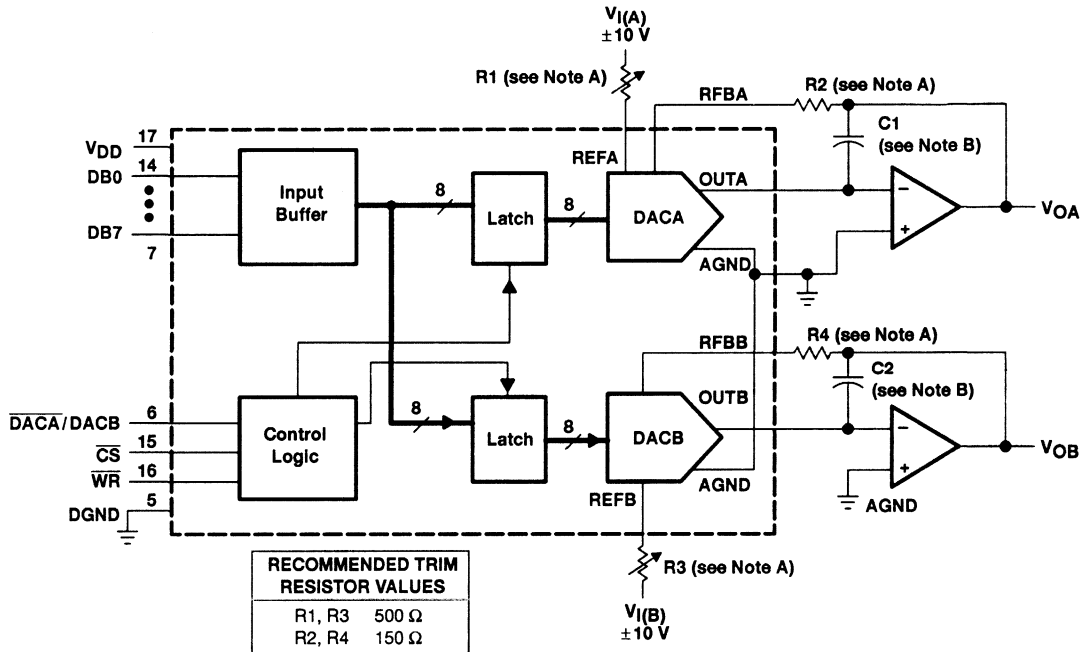
L = low level, H = high level, X = don't care

TLC7528C, TLC7528E, TLC7528I DUAL 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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APPLICATION INFORMATION

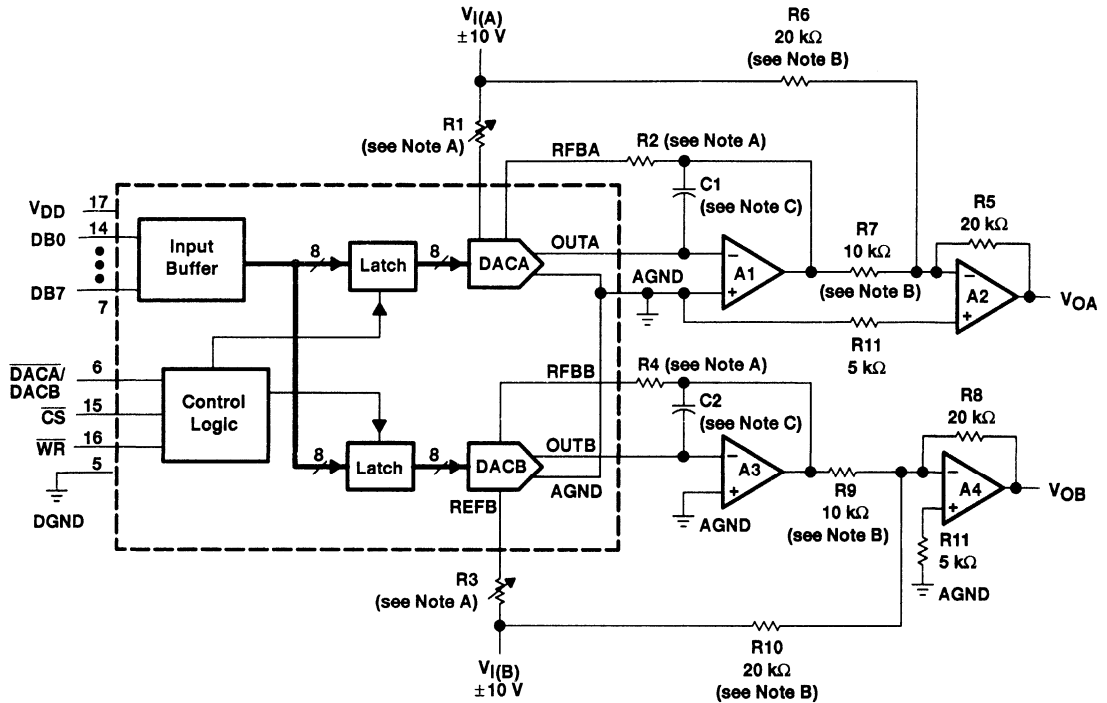
These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figures 3 and 4. Tables 1 and 2 summarize input coding for unipolar and bipolar operation.



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
- B. C1 and C2 phase compensation capacitors (10 pF to 15 pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

Figure 3. Unipolar Operation (2-Quadrant Multiplication)

APPLICATION INFORMATION



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table in Figure 3 for recommended values. Adjust R1 for $V_{OA} = 0\text{ V}$ with code 10000000 in DAC A latch. Adjust R3 for $V_{OB} = 0\text{ V}$ with 10000000 in DAC B latch.
 B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
 C. C1 and C2 phase compensation capacitors (10 pF to 15 pF) may be required if A1 and A3 are high-speed amplifiers.

Figure 4. Bipolar Operation (4-Quadrant Operation)

Table 1. Unipolar Binary Code

DAC LATCH CONTENTS		ANALOG OUTPUT
MSB	LSB [†]	
1	11111111	$-V_I (255/256)$
1	00000001	$-V_I (129/256)$
1	00000000	$-V_I (128/256) = -V_I/2$
0	11111111	$-V_I (127/256)$
0	00000001	$-V_I (1/256)$
0	00000000	$-V_I (0/256) = 0$

[†]1 LSB = $(2^{-8})V_I$

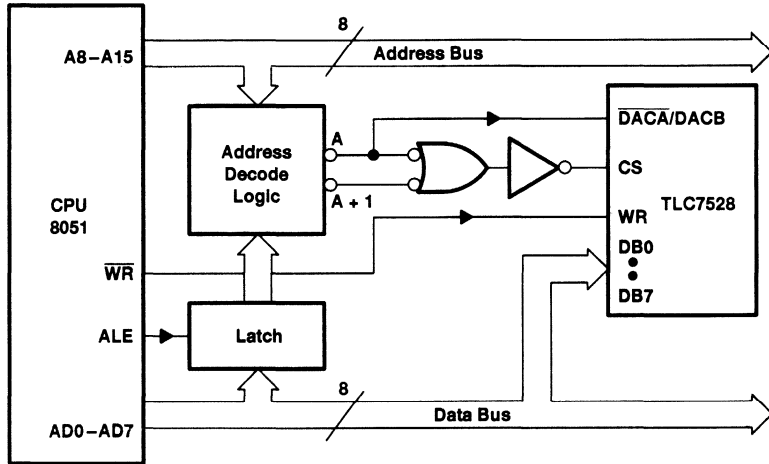
Table 2. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS		ANALOG OUTPUT
MSB	LSB [‡]	
1	11111111	$V_I (127/128)$
1	00000001	$V_I (1/128)$
1	00000000	0 V
0	11111111	$-V_I (1/128)$
0	00000001	$-V_I (127/128)$
0	00000000	$-V_I (128/128)$

[‡]1 LSB = $(2^{-7})V_I$

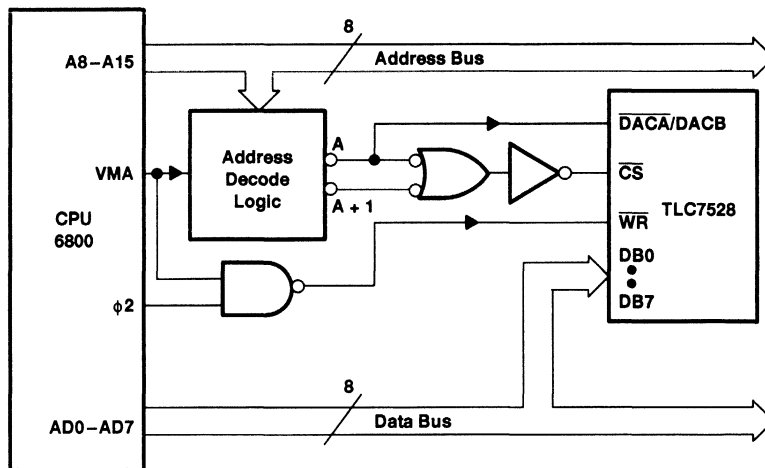
APPLICATION INFORMATION

microprocessor interface information



NOTE A: A = decoded address for TLC7528 DACA
 A + 1 = decoded address for TLC7528 DACB

Figure 5. TLC7528 - Intel 8051 Interface



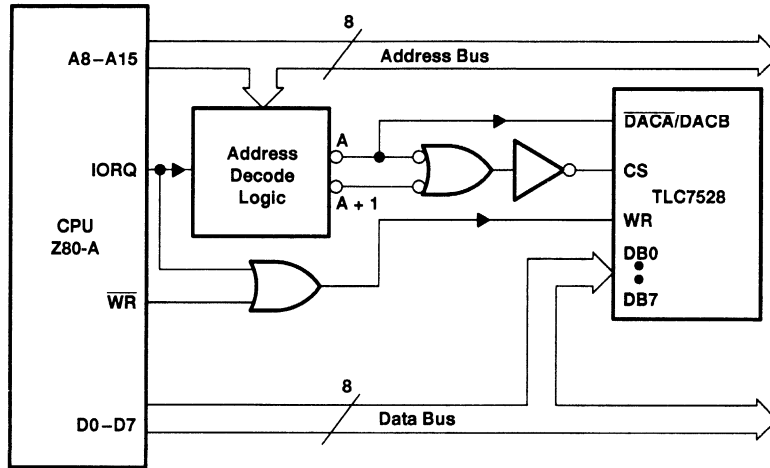
NOTE A: A = decoded address for TLC7528 DACA
 A + 1 = decoded address for TLC7528 DACB

Figure 6. TLC7528 - 6800 Interface

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APPLICATION INFORMATION



NOTE A: A = decoded address for TLC7528 DACA
 A + 1 = decoded address for TLC7528 DACB

Figure 7. TLC7528 To Z-80A Interface

programmable window detector

The programmable window comparator shown in Figure 8 determines if voltage applied to the DAC feedback resistors are within the limits programmed into the data latches of these devices. Input signal range depends on the reference and polarity, that is, the test input range is 0 to $-V_{ref}$. The DACA and DACB data latches are programmed with the upper and lower test limits. A signal within the programmed limits drives the output high.

APPLICATION INFORMATION

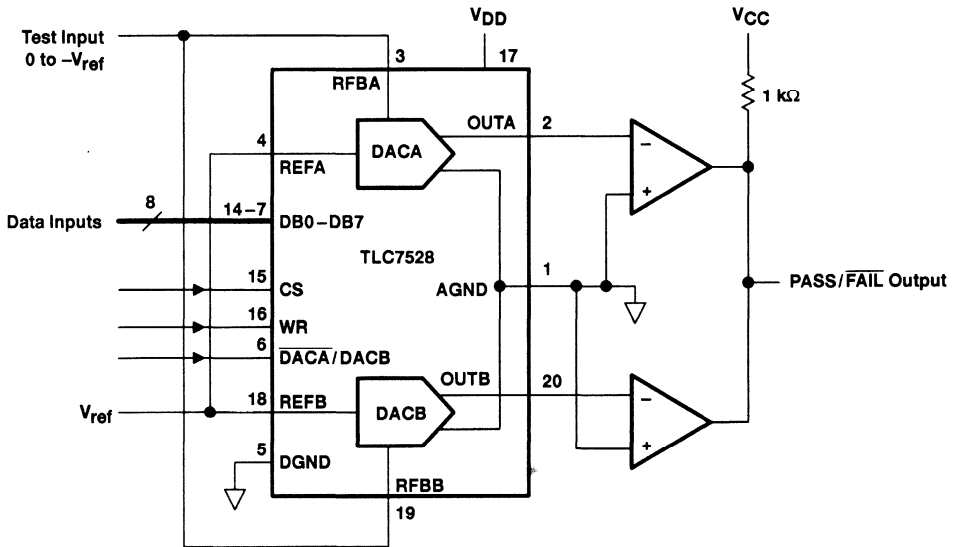


Figure 8. Digitally-Programmable Window Comparator (Upper- and Lower-Limit Tester)

digitally controlled signal attenuator

Figure 9 shows a TLC7528 configured as a two-channel programmable attenuator. Applications include stereo audio and telephone signal level control. Table 3 shows input codes vs attenuation for a 0 to 15.5 dB range.

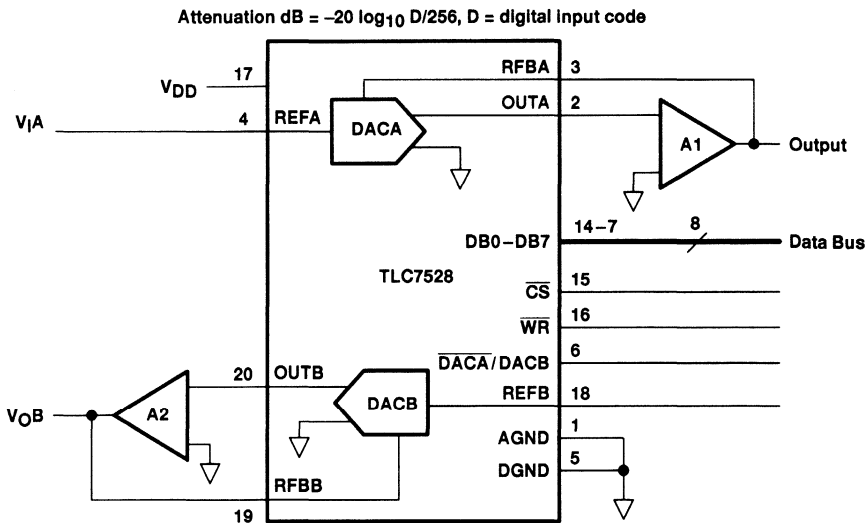


Figure 9. Digitally Controlled Dual Telephone Attenuator

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APPLICATION INFORMATION

Table 3. Attenuation vs DACA, DACB Code

ATTN (dB)	DAC INPUT CODE	CODE IN DECIMAL	ATTN (dB)	DAC INPUT CODE	CODE IN DECIMAL
0	11111111	255	8.0	01100110	102
0.5	11110010	242	8.5	01100000	96
1.0	11100100	228	9.0	01011011	91
1.5	11010111	215	9.5	01010110	86
2.0	11001011	203	10.0	01010001	81
2.5	11000000	192	10.5	01001100	76
3.0	10110101	181	11.0	01001000	72
3.5	10101011	171	11.5	01000100	68
4.0	10100010	162	12.0	01000000	64
4.5	10011000	152	12.5	00111101	61
5.0	10011111	144	13.0	00111001	57
5.5	10001000	136	13.5	00110110	54
6.0	10000000	128	14.0	00110011	51
6.5	01111001	121	14.5	00110000	48
7.0	01110010	114	15.0	00101110	46
7.5	01101100	108	15.5	00101011	43

programmable state-variable filter

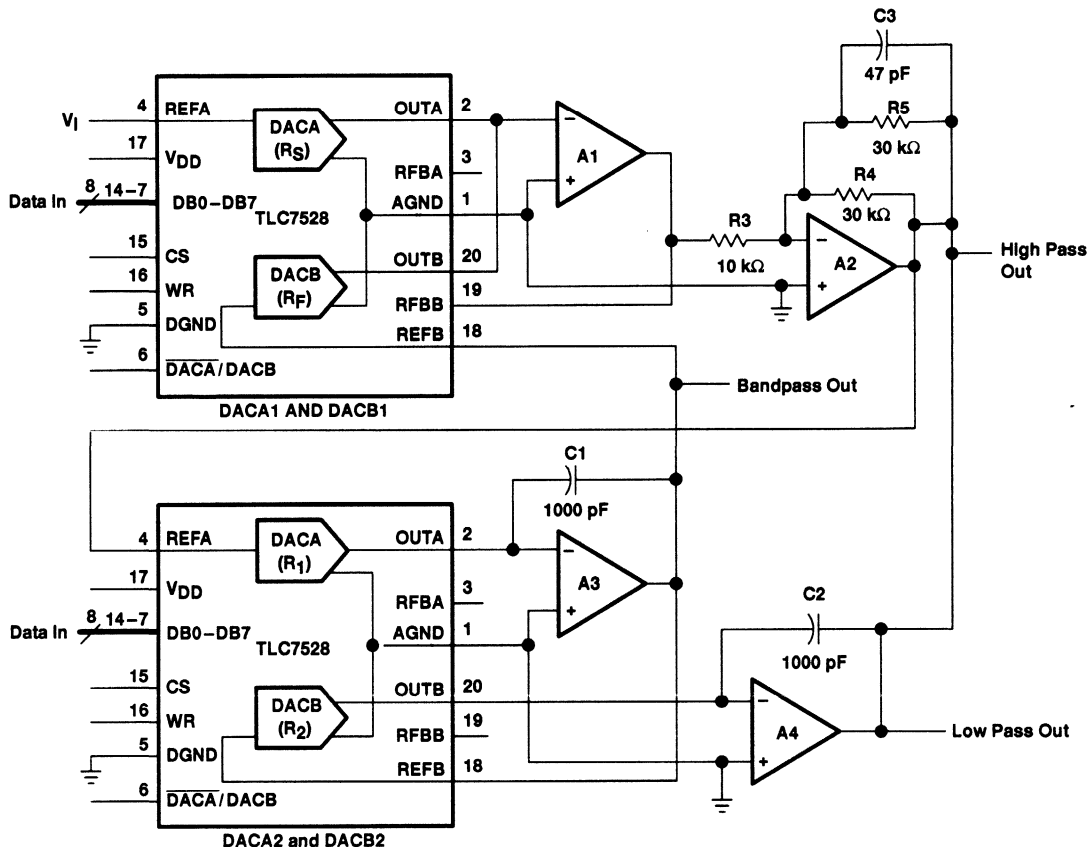
This programmable state-variable or universal filter configuration provides low-pass, high-pass, and bandpass outputs, and is suitable for applications requiring microprocessor control of filter parameters.

As shown in Figure 10, DACA1 and DACB1 control the gain and Q of the filter while DACA2 and DACB2 control the cutoff frequency. Both halves of the DACA2 and DACB2 must track accurately in order for the cutoff-frequency equation to be true. With the TLC7528, this is easy to achieve.

$$f_c = \frac{1}{2\pi R1C1}$$

The programmable range for the cutoff or center frequency is 0 to 15 kHz with a Q ranging from 0.3 to 4.5. This defines the limits of the component values.

APPLICATION INFORMATION



Circuit Equations:

$$C_1 = C_2, R_1 = R_2, R_4 = R_5$$

$$Q = \frac{R_3}{R_4} \cdot \frac{R_F}{R_{fb}(\text{DACB1})}$$

where:

R_{fb} is the internal resistor connected between OUTB and RFBB

$$G = -\frac{R_F}{R_S}$$

NOTES: A. Op-amps A1, A2, A3, and A4 are TL287.

B. CS compensates for the op-amp gain-bandwidth limitations.

C. DAC equivalent resistance equals $\frac{256 \times (\text{DAC ladder resistance})}{\text{DAC digital code}}$

Figure 10. Digitally Controlled State-Variable Filter

TLC7528C, TLC7528E, TLC7528I
DUAL 8-BIT MULTIPLYING
DIGITAL-TO-ANALOG CONVERTERS

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APPLICATION INFORMATION

voltage-mode operation

It is possible to operate the current multiplying D/A converter of these devices in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. Figure 11 is an example of a current multiplying D/A, that operates in the voltage mode.

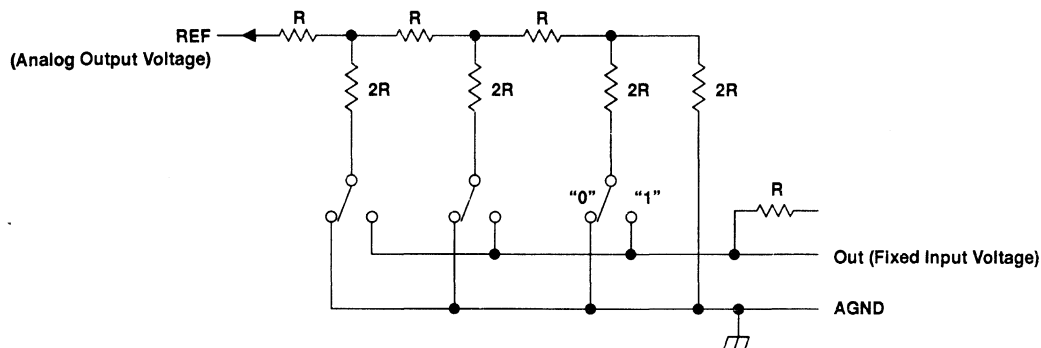


Figure 11. Voltage-Mode Operation

The following equation shows the relationship between the fixed input voltage and the analog output voltage:

$$V_O = V_I (D/256)$$

where

V_O = analog output voltage

V_I = fixed input voltage

D = digital input code converted to decimal

In voltage-mode operation, these devices meets the following specification:

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Linearity error at REFA or REFB	$V_{DD} = 5\text{ V}$, $OUTA$ or $OUTB$ at 2.5 V , $T_A = 25^\circ\text{C}$		1	LSB

TLC7628C, TLC7628E, TLC7628I DUAL 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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- Easy Microprocessor Interface
- On-Chip Data Latches
- Digital Inputs Are TTL-Compatible With 10.8-V to 15.75-V Power Supply
- Monotonic Over the Entire A/D Conversion Range
- Fast Control Signaling for Digital Signal Processor (DSP) Applications Including Interface With TMS320
- CMOS Technology

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 bits
Linearity Error	1/2 LSB
Power Dissipation	20 mW
Settling Time	100 ns
Propagation Delay Time	80 ns

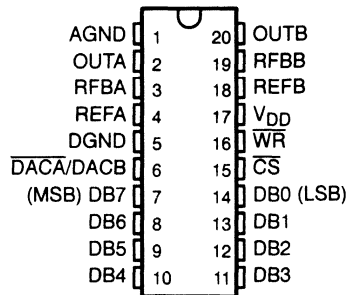
description

The TLC7628C, TLC7628E, and TLC7628I are dual, 8-bit, digital-to-analog converters (DACs) designed with separate on-chip data latches and feature exceptionally close DAC-to-DAC matching. Data is transferred to either of the two DAC data latches through a common, 8-bit input port. Control input $\overline{\text{DACA/DACB}}$ determines which DAC is loaded. The load cycle of these devices is similar to the write cycle of a random-access memory, allowing easy interface to most popular microprocessor buses and output ports. Segmenting the high-order bits minimizes glitches during changes in the most significant bits, where glitch impulse is typically the strongest.

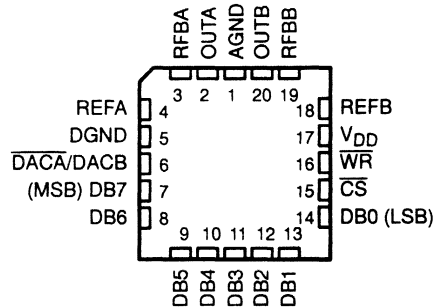
The TLC7628C operates from a 10.8-V to 15.75-V power supply and is TTL-compatible over this range. 2- or 4-quadrant multiplying makes these devices a sound choice for many microprocessor-controlled gain-setting and signal-control applications.

The TLC7628C is characterized for operation from 0°C to 70°C. The TLC7628I is characterized for operation from -25°C to 85°C. The TLC7628E is characterized for operation from -40°C to 85°C.

DW OR N PACKAGE
(TOP VIEW)



FN PACKAGE
(TOP VIEW)



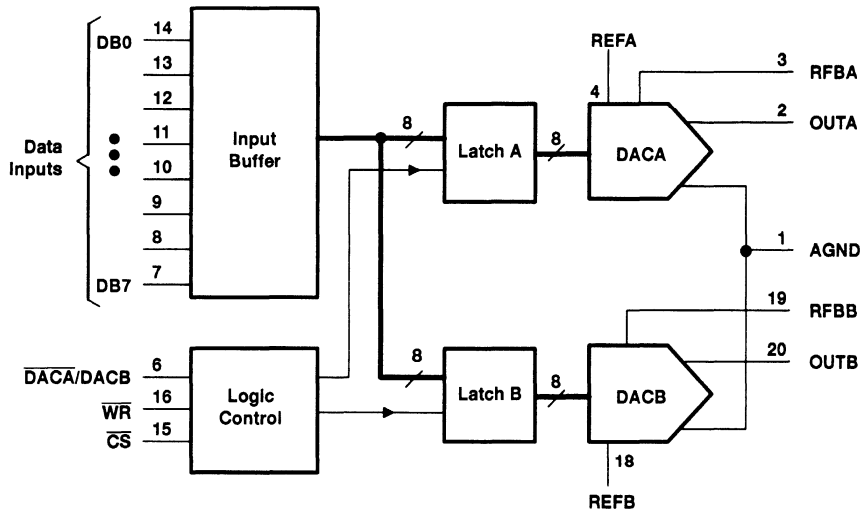
AVAILABLE OPTIONS

T _A	PACKAGE		
	SMALL OUTLINE PLASTIC DIP (DW)	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC7628CDW	TLC7628CFN	TLC7628CN
-25°C to 85°C	TLC7628IDW	TLC7628IFN	TLC7628IN
-40°C to 85°C	TLC7628EDW	TLC7628EFN	TLC7628EN

TLC7628C, TLC7628E, TLC7628I
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functional block diagram



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD} (to AGND or DGND)	-0.3 V to 17 V
Voltage between AGND and DGND	V_{DD}
Input voltage range, V_I (to DGND)	-0.3 V to $V_{DD} + 0.3$ V
Reference voltage range, V_{refA} or V_{refB} (to AGND)	± 25 V
Feedback voltage range, V_{RFBA} or V_{RFBB} (to AGND)	± 25 V
Output voltage range, V_{OA} or V_{OB} (to AGND)	± 25 V
Peak input current	10 μ A
Operating free-air temperature range, T_A :	
TLC7628C	0°C to 70°C
TLC7628I	-25°C to 85°C
TLC7628E	-40°C to 85°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds, T_C : FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: DW or N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

TLC7628C, TLC7628E, TLC7628I
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recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}		10.8		15.75	V
Reference voltage, V_{refA} or V_{refB}			± 10		V
High-level input voltage, V_{IH}		2.4			V
Low-level input voltage, V_{IL}				0.8	V
\overline{CS} setup time, $t_{su}(CS)$		50			ns
\overline{CS} hold time, $t_h(CS)$ (see Figure 1)		0			ns
DAC select setup time, $t_{su}(DAC)$ (see Figure 1)		60			ns
DAC select hold time, $t_h(DAC)$ (see Figure 1)		10			ns
Data bus input setup time $t_{su}(D)$ (see Figure 1)		25			ns
Data bus input hold time $t_h(D)$ (see Figure 1)		10			ns
Pulse duration, \overline{WR} low, $t_w(WR)$ (see Figure 1)		50			ns
Operating free-air temperature, T_A	TLC7628C	0		70	°C
	TLC7628I	-25		85	
	TLC7628E	-40		85	

electrical characteristics over recommended ranges of operating free-air temperature and V_{DD} , $V_{refA} = V_{refB} = 10$ V, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	MAX	UNIT		
I_{IH}	High-level input current	$V_I = V_{DD}$	Full range		10	μA		
			25°C		1			
I_{IL}	Low-level input current	$V_I = 0$	Full range		-10	μA		
			25°C		-1			
Reference input impedance REFA or REFB to AGND				5	20	k Ω		
I_{kg}	Output leakage current	OUTA	DAC data latch loaded with 00000000, $V_{refA} = \pm 10$ V	Full range		± 200		
				25°C		± 50		
				Full range		± 200		
				25°C		± 50		
Input resistance match (REFA to REFB)						$\pm 1\%$		
DC supply sensitivity $\Delta gain/\Delta V_{DD}$		$\Delta V_{DD} = \pm 5\%$	Full range		0.02	%/%		
			25°C		0.01			
I_{DD}	Supply current	Quiescent	All digital inputs at V_{IHmin} or V_{ILmax}		2	mA		
			Standby	All digital inputs at 0 V or V_{DD}			Full range	0.5
				25°C			0.1	
C_i	Input capacitance	DB0-DB7			10	pF		
		\overline{WR} , \overline{CS} , DACA/DACB			15			
C_o	Output capacitance (OUTA, OUTB)	DAC data latches loaded with 00000000		25	pF			
		DAC data latches loaded with 11111111		60				

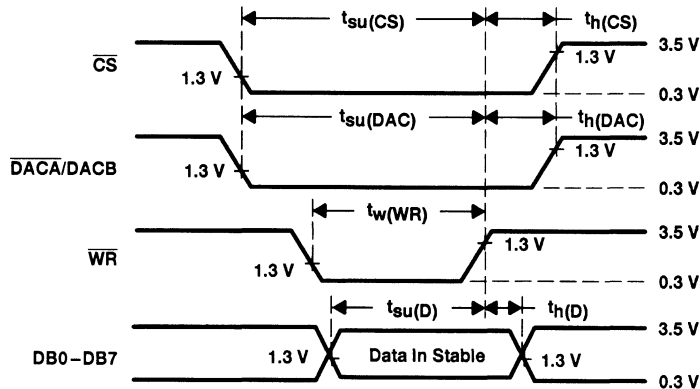
TLC7628C, TLC7628E, TLC7628I DUAL 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

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operating characteristics over recommended ranges of operating free-air temperature and V_{DD} , $V_{refA} = V_{refB} = 10\text{ V}$, V_{OA} and V_{OB} at 0 V (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Linearity error				$\pm 1/2$		LSB
Settling time (to 1/2 LSB)		See Note 1			100	ns
Gain error		See Note 2	Full range 25°C		± 3	LSB
					± 2	
AC feedthrough	REFA to OUTA	See Note 3	Full range 25°C		-65	dB
	REFB to OUTB				-75	
Temperature coefficient of gain					± 0.0035	%FSR/°C
Propagation delay (from digital input to 90% of final analog output current)		See Note 4			80	ns
Channel-to-channel isolation	REFA to OUTB	See Note 5	25°C	80		dB
	REFB to OUTA	See Note 6	25°C	80		
Digital-to-analog glitch impulse area		Measured for code transition from 00000000 to 11111111, $T_A = 25^\circ\text{C}$		330		nV•s
Digital crosstalk		Measured for code transition from 00000000 to 11111111, $T_A = 25^\circ\text{C}$		60		nV•s
Harmonic distortion		$V_i = 6\text{ V}$, $f = 1\text{ kHz}$, $T_A = 25^\circ\text{C}$		-85		dB

- NOTES: 1. OUTA, OUTB load = $100\ \Omega$, $C_{ext} = 13\text{ pF}$; \overline{WR} and \overline{CS} at 0 V ; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V .
 2. Gain error is measured using an internal feedback resistor. Nominal full scale range (FSR) = $V_{ref} - 1\text{ LSB}$. Both DAC latches are loaded with 11111111.
 3. $V_{ref} = 20\text{ V}$ peak-to-peak, 10-kHz sine wave
 4. $V_{refA} = V_{refB} = 10\text{ V}$; OUTA/OUTB load = $100\ \Omega$, $C_{ext} = 13\text{ pF}$; \overline{WR} and \overline{CS} at 0 V ; DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V .
 5. $V_{refA} = 20\text{ V}$ peak-to-peak, 10-kHz sine wave; $V_{refB} = 0$
 6. $V_{refB} = 20\text{ V}$ peak-to-peak, 10-kHz sine wave; $V_{refA} = 0$

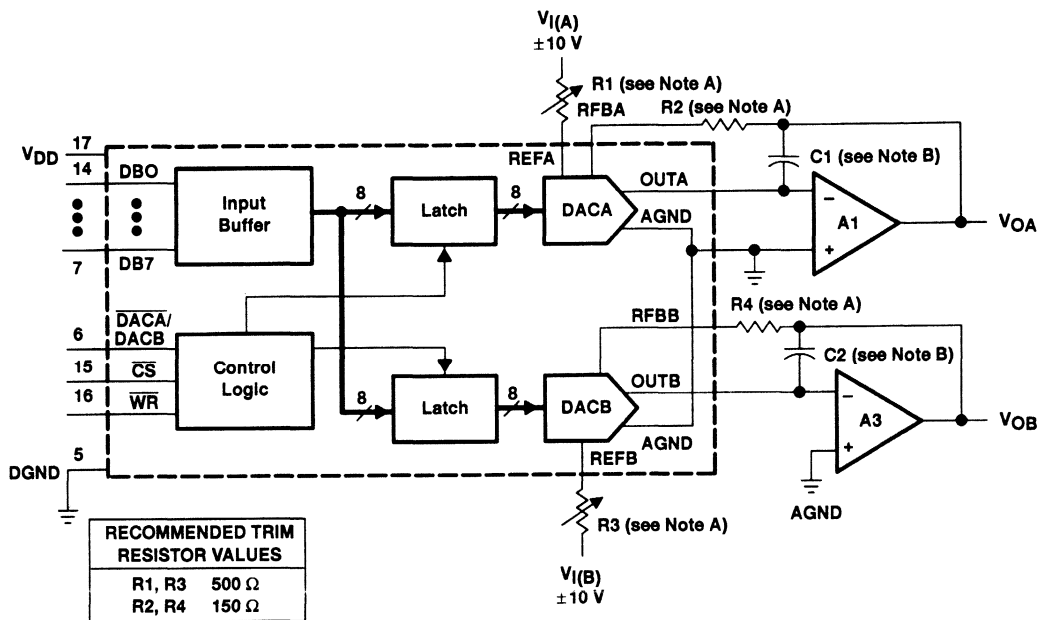


For all input signals, $t_r = t_f = 5\text{ ns}$ (10% to 90% points).

Figure 1. Setup and Hold Times

APPLICATION INFORMATION

These devices are capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant and 4-quadrant multiplication are shown in Figures 2 and 3. Input coding for unipolar and bipolar operation are summarized in Tables 2 and 3, respectively.



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Make gain adjustment with digital input of 255.
 B. C1 and C2 phase compensation capacitors (10 pF to 15 pF) are required when using high-speed amplifiers to prevent ringing or oscillation.

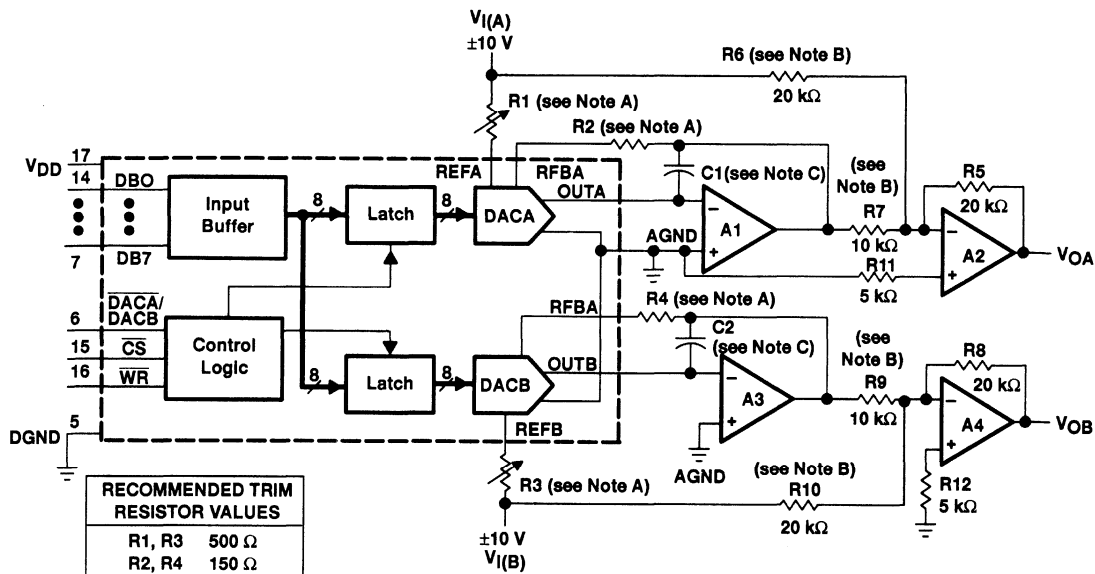
Figure 2. Unipolar Operation (2-Quadrant Multiplication)

TLC7628C, TLC7628E, TLC7628I

DUAL 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTERS

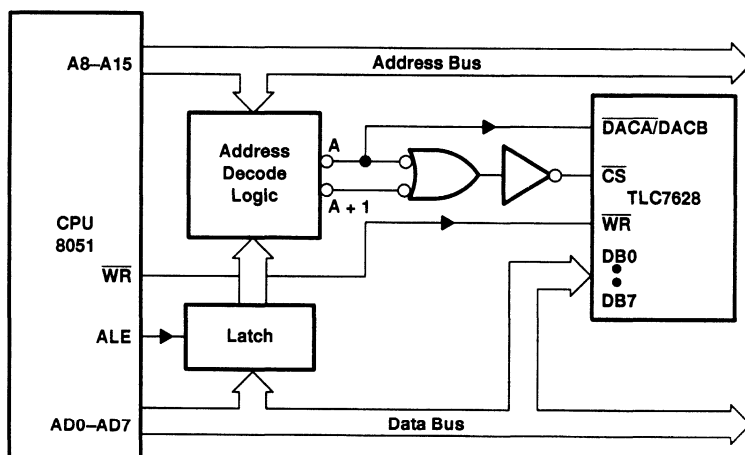
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APPLICATION INFORMATION



- NOTES: A. R1, R2, R3, and R4 are used only if gain adjustment is required. See table for recommended values. Adjust R1 for $V_{OA} = 0$ V with code 10000000 in DACA latch. Adjust R3 for $V_{OB} = 0$ V with 10000000 in DACB latch.
- B. Matching and tracking are essential for resistor pairs R6, R7, R9, and R10.
- C. C1 and C2 phase compensation capacitors (10 pF to 15 pF) may be required if A1 and A3 are high-speed amplifiers.

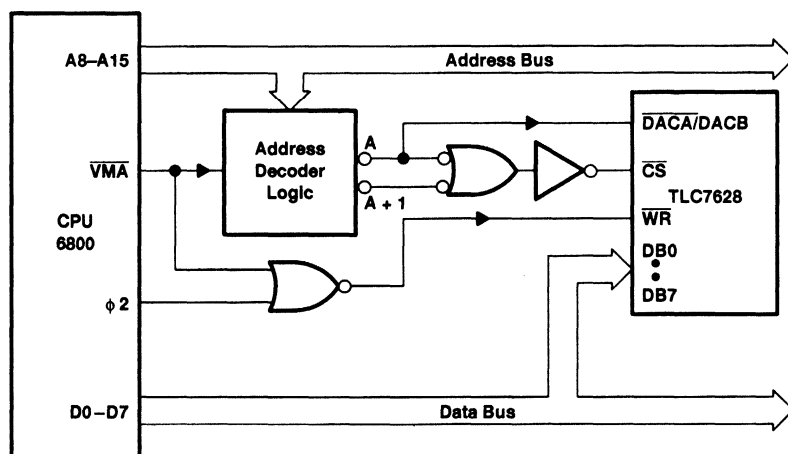
Figure 3. Bipolar Operation (4-Quadrant Operation)



NOTE A: A = decoded address for TLC7628 DACA
 A + 1 = decoded address for TLC7628 DACB

Figure 4. TLC7628 — Intel 8051 Interface

APPLICATION INFORMATION



NOTE A: A = decoded address for TLC7628 DACA
 A + 1 = decoded address for TLC7628 DACB

Figure 5. TLC7628 - 6800 Interface

voltage-mode operation

The current-multiplying DAC in these devices can be operated in a voltage mode. In the voltage mode, a fixed voltage is placed on the current output terminal. The analog output voltage is then available at the reference voltage terminal. An example of a current-multiplying DAC operating in voltage mode is shown in Figure 6. The relationship between the fixed input voltage and the analog output voltage is given by the following equation:

$$\text{Analog output voltage} = \text{fixed input voltage} (D/256)$$

where D = the digital input. In voltage-mode operation, these devices meet the following specification:

LINEARITY ERROR	TEST CONDITIONS	MIN	MAX	UNIT
Analog output voltage for REFA, REFB	V _{DD} = 12 V, OUTA or OUTB at 5 V, T _A = 25°C		1	LSB

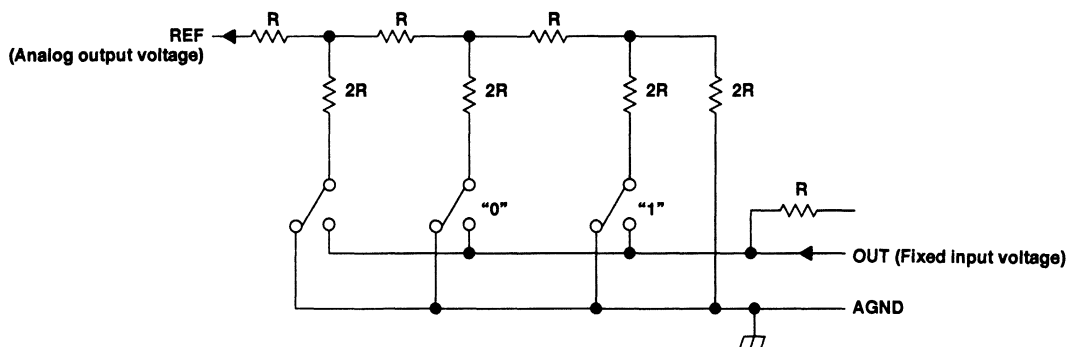


Figure 6. Current-Multiplying DAC Operating in Voltage Mode

TLC7628C, TLC7628E, TLC7628I
DUAL 8-BIT MULTIPLYING
DIGITAL-TO-ANALOG CONVERTERS

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PRINCIPLES OF OPERATION

These devices contain two, identical, 8-bit, multiplying DACs, DACA and DACB. Each DAC consists of an inverted R-2R ladder, analog switches, and input data latches. Binary-weighted currents are switched between the DAC output and AGND, thus maintaining a constant current in each ladder leg independent of the switch state. Most applications require only the addition of an external operational amplifier and voltage reference. A simplified D/A circuit for DACA or DACB with all digital inputs low is shown in Figure 7.

Figure 8 shows the DACA or DACB equivalent circuit. Both DACs share the analog ground terminal 1 (AGND). With all digital inputs high, the reference current flows to OUTA. A small leakage current (I_{lkg}) flows across internal junctions, and as with most semiconductor devices, doubles every 10°C. The C_o is caused by the parallel combination of the NMOS switches and has a value that depends on the number of switches connected to the output. The range of C_o is 25 pF to 60 pF maximum. The equivalent output resistance (r_o) varies with the input code from 0.8R to 3R where R is the nominal value of the ladder resistor in the R-2R network.

These devices interface to a microprocessor through the data bus, \overline{CS} , \overline{WR} , and $\overline{DACA/DACB}$ control signals. When \overline{CS} and \overline{WR} are both low, the analog output on these devices, specified by the $\overline{DACA/DACB}$ control line, responds to the activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the \overline{CS} signal or \overline{WR} signal goes high, the data on the DB0–DB7 inputs is latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled, regardless of the state of the \overline{WR} signal.

The digital inputs of these devices provide TTL compatibility when operated from a supply voltage of 10.8 V to 15.75 V.

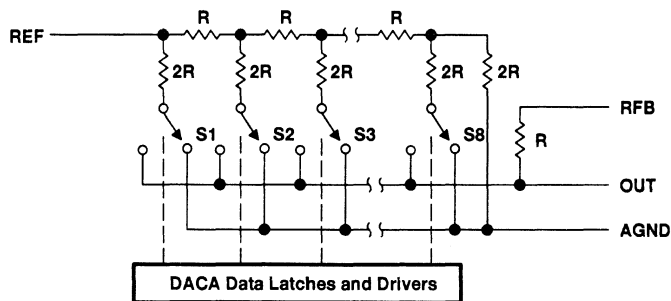


Figure 7. Simplified Functional Circuit for DACA or DACB

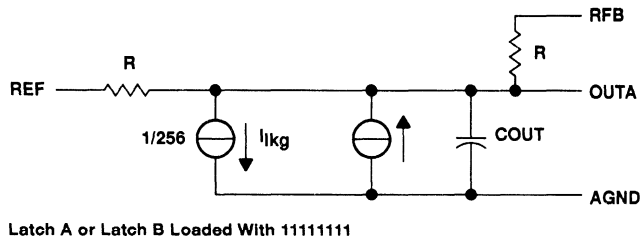


Figure 8. TLC7628 Equivalent Circuit for DACA or DACB

TLC7628C, TLC7628E, TLC7628I
DUAL 8-BIT MULTIPLYING
DIGITAL-TO-ANALOG CONVERTERS
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PRINCIPLES OF OPERATION

Table 1. MODE SELECTION TABLE

DACĀ/DACB	C \bar{S}	WR	DACA	DACB
L	L	L	Write	Hold
H	L	L	Hold	Write
X	H	X	Hold	Hold
X	X	H	Hold	Hold

L = low level, H = high level, X = don't care

Table 2. Unipolar Binary Code

DAC LATCH CONTENTS (see Note 7)		ANALOG OUTPUT
MSB	LSB	
1	1111111	$-V_I (255/256)$
1	0000001	$-V_I (129/256)$
1	0000000	$-V_I (128/256) = -V_I / 2$
0	1111111	$-V_I (127/256)$
0	0000001	$-V_I (1/256)$
0	0000000	$-V_I (0/256) = 0$

Table 3. Bipolar (Offset Binary) Code

DAC LATCH CONTENTS (see Note 8)		ANALOG OUTPUT
MSB	LSB	
1	1111111	$V_I (127/128)$
1	0000001	$V_I (1/128)$
1	0000000	0 V
0	1111111	$-V_I (1/128)$
0	0000001	$-V_I (127/128)$
0	0000000	$-V_I (128/128)$

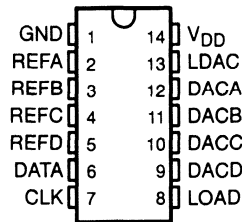
NOTES: 7. 1 LSB = $(2^{-8})V_I$
 8. 1 LSB = $(2^{-7})V_I$

TLV5620C, TLV5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS110 – JANUARY 1995

- Four 8-Bit Voltage Output DACs
- 3-V Single-Supply Operation
- Serial Interface
- High-Impedance Reference Inputs
- Programmable 1 or 2 Times Output Range
- Simultaneous-Update Facility
- Internal Power-On Reset
- Low Power Consumption
- Half-Buffered Output

N OR D PACKAGE
(TOP VIEW)



applications

- Programmable Voltage Sources
- Digitally-Controlled Amplifiers/Attenuators
- Mobile Communications
- Automatic Test Equipment
- Process Monitoring and Control
- Signal Synthesis

description

The TLV5620C and TLV5620I are quadruple 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND and the DACs are monotonic. The device is simple to use, running from a single supply of 3 to 3.6 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLV5620C and TLV5620I are over a simple 3-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 11-bit command word comprises 8 bits of data, 2 DAC select bits and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs updated simultaneously through control of the LDAC terminal. The digital inputs feature Schmitt triggers for high noise immunity.

The 14-terminal small-outline (SO) package allows digital control of analog functions in space-critical applications. The TLV5620C is characterized for operation from 0°C to 70°C. The TLV5620I is characterized for operation from –40°C to 85°C. The TLV5620C and TLV5620I do not require external trimming.

AVAILABLE OPTIONS

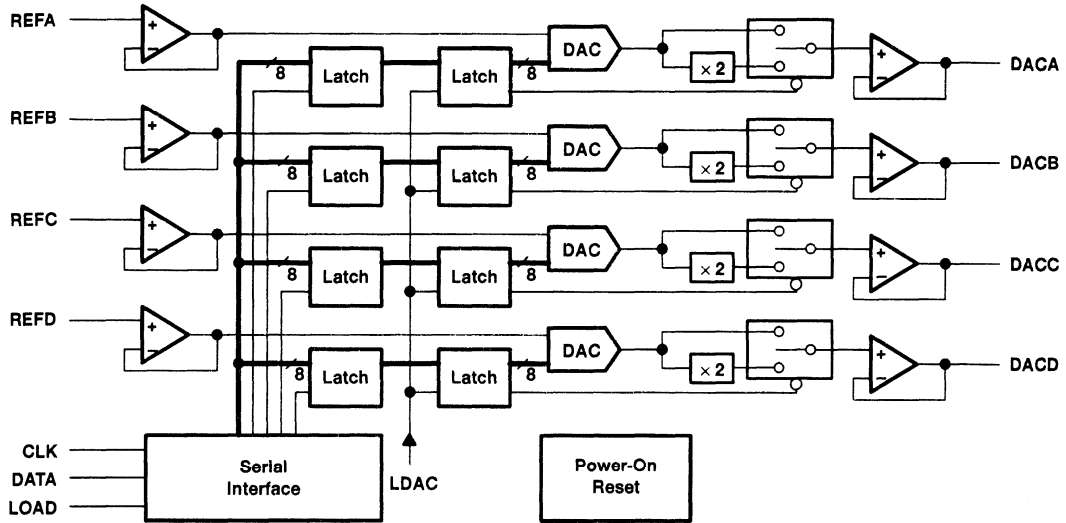
T _A	PACKAGE	
	SMALL OUTLINE (D)	PLASTIC DIP (N)
0°C to 70°C	TLV5620CD	TLV5620CN
–40°C to 85°C	TLV5620ID	TLV5620IN

PRODUCT PREVIEW

TLV5620C, TLV5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
CLK	7	I	Serial-interface clock, data enters on the negative edge
DACA	12	O	DAC A analog output
DACB	11	O	DAC B analog output
DACC	10	O	DAC C analog output
DACD	9	O	DAC D analog output
DATA	6	I	Serial-interface digital-data input
GND	1	I	Ground return and reference terminal
LDAC	13	I	DAC-update latch control
LOAD	8	I	Serial-interface load control
REFA	2	I	Reference voltage input to DACA
REFB	3	I	Reference voltage input to DACB
REFC	4	I	Reference voltage input to DACC
REFD	5	I	Reference voltage input to DACD
V _{DD}	14	I	Positive supply voltage

detailed description

The TLV5620 is implemented using four resistor-string digital-to-analog converters (DACs). The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 2. One end of each resistor string is connected to the GND terminal and the other end is fed from the output of the reference input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor elements and upon the performance of the output buffer. Because the inputs are buffered, the DACs always presents a high-impedance load to the reference source.

PRODUCT PREVIEW



detailed description (continued)

Each DAC output is buffered by a configurable-gain output amplifier, which can be programmed to times 1 or times 2 gain.

On powerup, the DACs are reset to CODE 0.

Each output voltage is given by:

$$V_O(\text{DACA/BICID}) = \text{REF} \times \frac{\text{CODE}}{256} \times (1 + \text{RNG bit value})$$

where CODE is in the range 0 to 255 and the range (RNG) bit is a 0 or 1 within the serial-control word.

data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial-input register to the selected DAC as shown in Figure 1. If LDAC is low, the selected DAC output voltage is updated and LOAD goes low. If LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered MSB first.

PRODUCT PREVIEW

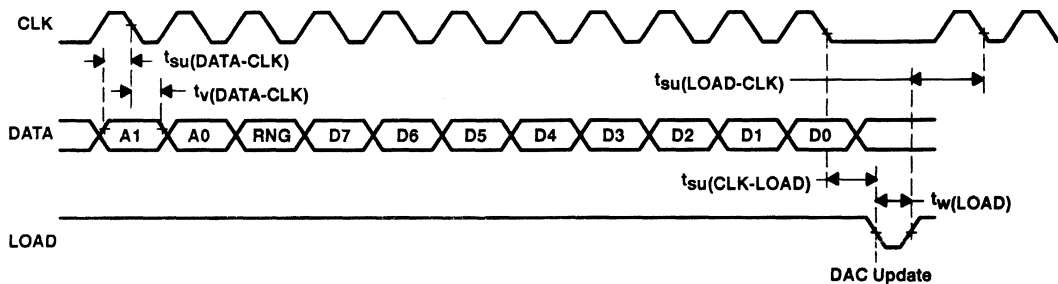


Figure 1. LOAD-Controlled Update (LDAC = Low)

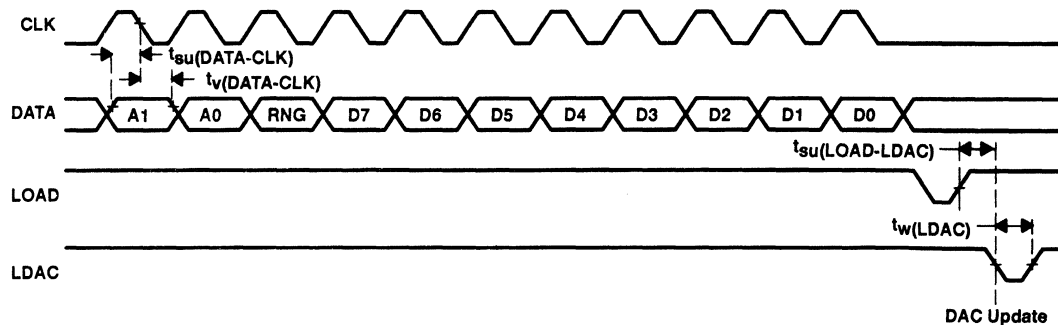


Figure 2. LDAC-Controlled Update

data interface (continued)

Table 1 lists the A1 and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

PRODUCT PREVIEW

TLV5620C, TLV5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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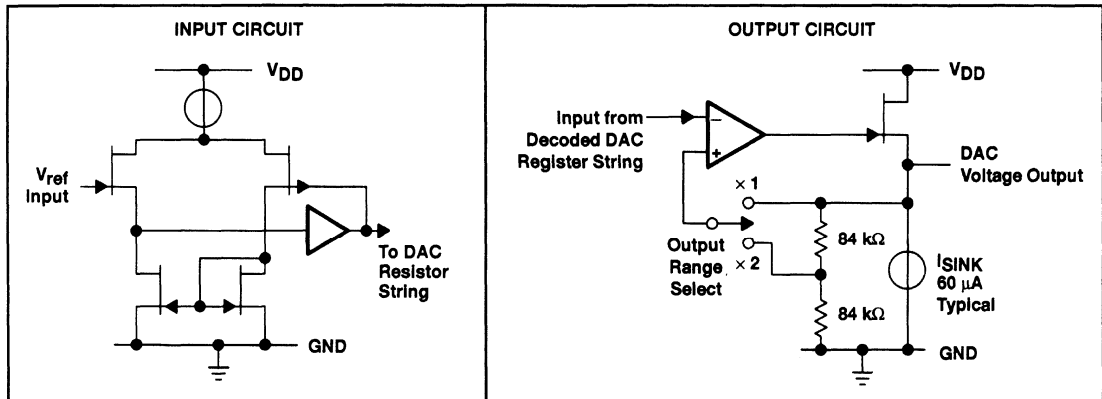
Table 1. Serial-Input Decode

A1	A0	DAC UPDATED
0	0	DACA
0	1	DACB
1	0	DACC
1	1	DACD

Table 2. Ideal-Output Transfer

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	$(1/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	$(127/256) \times \text{REF} (1+\text{RNG})$
1	0	0	0	0	0	0	0	$(128/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	$(255/256) \times \text{REF} (1+\text{RNG})$

equivalent inputs and outputs



TLV5620C, TLV5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage ($V_{DD} - GND$)	7 V
Digital input voltage range	$GND - 0.3\text{ V to }V_{DD} + 0.3\text{ V}$
Reference input voltage range, V_{ID}	$GND - 0.3\text{ V to }V_{DD} + 0.3\text{ V}$
Operating free-air temperature range, T_A : TLV5620C	$0^\circ\text{C to }70^\circ\text{C}$
TLV5620I	$-40^\circ\text{C to }85^\circ\text{C}$
Storage temperature range, T_{stg}	$-50^\circ\text{C to }150^\circ\text{C}$
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	230°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	2.7	3.3	5.25	V
High-level digital input voltage, V_{IH}	0.8 V_{DD}			V
Low-level digital input voltage, V_{IL}	0.8			V
Reference voltage, V_{ref} [AIBICID], x1 gain	$V_{DD} - 1.5$			V
Load resistance, R_L	10			k Ω
Setup time, data input, $t_{su}(\text{DATA-CLK})$ (see Figures 1 and 2)	50			ns
Valid time, data input valid after $\text{CLK}\downarrow$, $t_v(\text{DATA-CLK})$ (see Figures 1 and 2)	50			ns
Setup time, CLK eleventh falling edge to LOAD, $t_{su}(\text{CLK-LOAD})$ (see Figure 1)	50			ns
Setup time, $\text{LOAD}\uparrow$ to $\text{CLK}\downarrow$, $t_{su}(\text{LOAD-CLK})$ (see Figure 1)	50			ns
Pulse duration, LOAD, $t_w(\text{LOAD})$ (see Figure 1)	250			ns
Pulse duration, LDAC, $t_w(\text{LDAC})$ (see Figure 2)	250			ns
Setup time, $\text{LOAD}\uparrow$ to $\text{LDAC}\downarrow$, $t_{su}(\text{LOAD-LDAC})$ (see Figure 2)	0			ns
CLK frequency	1			MHz
Operating free-air temperature, T_A	TLV5620C	0		70°C
	TLV5620I	-40		85°C

PRODUCT PREVIEW



TLV5620C, TLV5620I QUADRUPLE 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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**electrical characteristics over recommended operating free-air temperature range,
 $V_{DD} = 3\text{ V}$ to 3.6 V , $V_{ref} = 2\text{ V}$, $\times 1$ gain output range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{IH}	High-level digital input current	$V_I = V_{DD}$			± 10	μA
I_{IL}	Low-level digital input current	$V_I = 0\text{ V}$			± 10	μA
$I_{O(sink)}$	Output sink current	Each DAC output		20		μA
$I_{O(source)}$	Output source current			2		mA
C_i	Input capacitance			15		pF
	Reference input capacitance			15		
I_{DD}	Supply current	$V_{DD} = 3.3\text{ V}$			2	mA
I_{ref}	Reference input current	$V_{DD} = 3.3\text{ V}$, $V_{ref} = 1.5\text{ V}$			± 10	μA
E_L	Linearity error (end point corrected)	$V_{ref} = 1.25\text{ V}$, $\times 2$ gain (see Note 1)			± 1	LSB
E_D	Differential linearity error	$V_{ref} = 1.25\text{ V}$, $\times 2$ gain (see Note 2)			± 0.9	LSB
E_{ZS}	Zero-scale error	$V_{ref} = 1.25\text{ V}$, $\times 2$ gain (see Note 3)	0		30	mV
	Zero-scale error temperature coefficient	$V_{ref} = 1.25\text{ V}$, $\times 2$ gain (see Note 4)		10		$\mu\text{V}/^\circ\text{C}$
E_{FS}	Full-scale error	$V_{ref} = 1.25\text{ V}$, $\times 2$ gain (see Note 5)			± 60	mV
	Full-scale error temperature coefficient	$V_{ref} = 1.25\text{ V}$, $\times 2$ gain (see Note 6)		± 25		$\mu\text{V}/^\circ\text{C}$
PSRR	Power-supply sensitivity	See Notes 7 and 8		0.5		mV/V

- NOTES: 1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero and full scale (excluding the effects of zero code and full-scale errors).
2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
4. Zero-scale error temperature coefficient is given by: $ZSETC = [ZSE(T_{max}) - ZSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
5. Full-scale error is the deviation from the ideal full-scale output ($V_{ref} - 1\text{ LSB}$) with an output load of $10\text{ k}\Omega$.
6. Full-scale temperature coefficient is given by: $FSETC = [FSE(T_{max}) - FSE(T_{min})]/V_{ref} \times 10^6/(T_{max} - T_{min})$.
7. Zero-scale error rejection ratio (ZSE-RR) is measured by varying the V_{DD} voltage from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
8. Full-scale error rejection ratio (FSE-RR) is measured by varying the V_{DD} from 3.0 V to 3.6 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

**operating characteristics over recommended operating free-air temperature range,
 $V_{DD} = 3\text{ V}$ to 3.6 V , $V_{ref} = 2\text{ V}$, $\times 1$ gain output range (unless otherwise noted)**

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	$C_L = 100\text{ pF}$, $R_L = 10\text{ k}\Omega$		1		$\text{V}/\mu\text{s}$
Output settling time	To 0.5 LSB, $C_L = 100\text{ pF}$, $R_L = 10\text{ k}\Omega$, See Note 9		10		μs
Large-signal bandwidth	Measured at -3 dB point		100		kHz
Digital crosstalk	$\text{CLK} = 1\text{-MHz}$ square wave measured at DACA-DACD		-50		dB
Reference feedthrough	See Note 10		-60		dB
Channel-to-channel isolation	See Note 11		-60		dB
Reference input bandwidth	See Note 12		100		kHz

- NOTES: 9. Settling time is the time for the output signal to remain within $\pm 0.5\text{ LSB}$ of the final measured value for a digital input code change of 00 hex to FF hex or FF hex to 00 hex. For TLV5620C: $V_{DD} = 5\text{ V}$, $V_{ref} = 2\text{ V}$ and range = $\times 2$. For TLV5620I: $V_{DD} = 3\text{ V}$, $V_{ref} = 1.25\text{ V}$ and range $\times 2$.
10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz .
11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex with V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz .
12. Reference bandwidth is the -3 dB bandwidth with an input at $V_{ref} = 1.25\text{ V}$ dc + 2 V_{pp} , with a digital input code of full-scale.

PRODUCT PREVIEW



PARAMETER MEASUREMENT INFORMATION

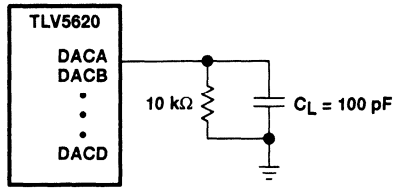
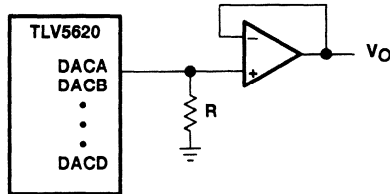


Figure 3. Slewing Settling Time and Linearity Measurements

APPLICATION INFORMATION



NOTE A: Resistor $R \geq 10\text{ k}\Omega$

Figure 4. Output Buffering Schemes

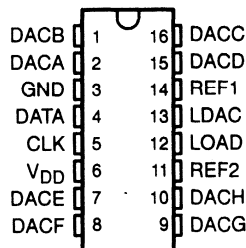
PRODUCT PREVIEW

TLV5628C, TLV5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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- Eight 8-Bit Voltage Output DACs
- 3-V Single-Supply Operation
- Serial Interface
- High-Impedance Reference Inputs
- Programmable 1 or 2 Times Output Range
- Simultaneous-Update Facility
- Internal Power-On Reset
- Low Power Consumption
- Half-Buffered Output

N OR D PACKAGE
(TOP VIEW)



applications

- Programmable Voltage Sources
- Digitally-Controlled Amplifiers/Attenuators
- Mobile Communications
- Automatic Test Equipment
- Process Monitoring and Control
- Signal Synthesis

description

The TLV5628C and TLV5628I are octal 8-bit voltage output digital-to-analog converters (DACs) with buffered reference inputs (high impedance). The DACs produce an output voltage that ranges between either one or two times the reference voltages and GND, and the DACs are monotonic. The device is simple to use, running from a single supply of 3 to 3.6 V. A power-on reset function is incorporated to ensure repeatable start-up conditions.

Digital control of the TLV5628C and TLV5628I is over a simple 3-wire serial bus that is CMOS compatible and easily interfaced to all popular microprocessor and microcontroller devices. The 12-bit command word comprises 8 bits of data, 3 DAC select bits and a range bit, the latter allowing selection between the times 1 or times 2 output range. The DAC registers are double buffered, allowing a complete set of new values to be written to the device, then all DAC outputs updated simultaneously through control of the LDAC terminal. The digital inputs feature Schmitt triggers for high noise immunity.

The 16-terminal small-outline D package allows digital control of analog functions in space-critical applications. The TLV5628C is characterized for operation from 0°C to 70°C. The TLV5628I is characterized for operation from -40°C to 85°C. The TLV5628C and TLV5628I do not require external trimming.

AVAILABLE OPTIONS

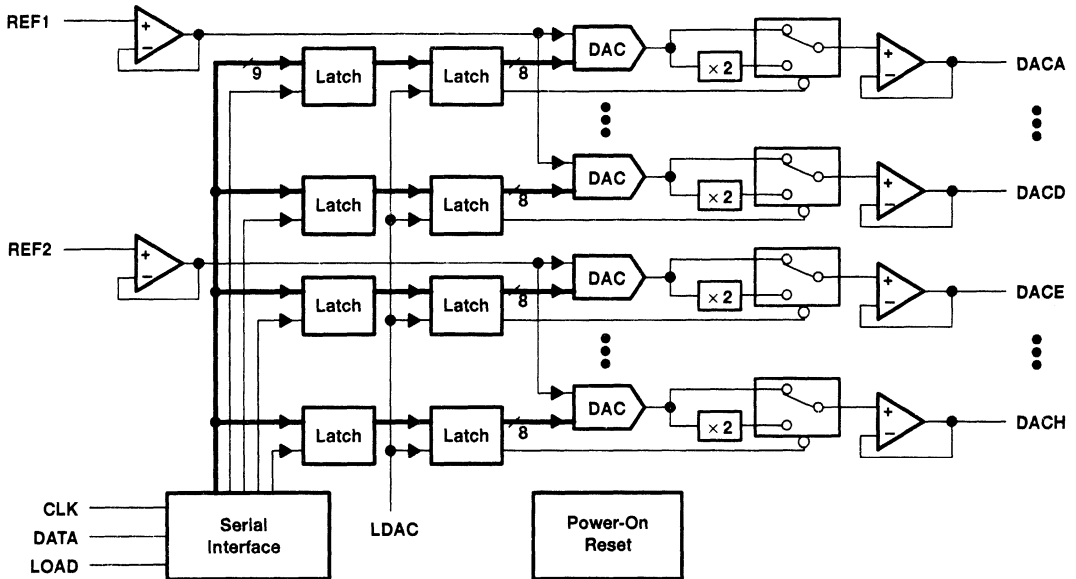
T _A	PACKAGE	
	SMALL OUTLINE (D)	PLASTIC DIP (N)
0°C to 70°C	TLV5628CD	TLV5628CN
-40°C to 85°C	TLV5628ID	TLV5628IN

PRODUCT PREVIEW

TLV5628C, TLV5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
CLK	5	I	Serial-interface clock, data enters on the negative edge
DACA	2	O	DACA analog output
DACB	1	O	DACB analog output
DACC	16	O	DACC analog output
DACD	15	O	DACD analog output
DACE	7	O	DACE analog output
DACF	8	O	DACF analog output
DACG	9	O	DACG analog output
DACH	10	O	DACH analog output
DATA	4	I	Serial-interface digital data input
GND	3	I	Ground return and reference terminal
LDAC	13	I	DAC-update latch control
LOAD	12	I	Serial-interface load control
REF1	14	I	Reference voltage input to DACA
REF2	11	I	Reference voltage input to DACB
VDD	6	I	Positive supply voltage

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detailed description

The TLV5628 is implemented using eight resistor-string DACs. The core of each DAC is a single resistor with 256 taps, corresponding to the 256 possible codes listed in Table 2. One end of each resistor string is connected to the GND terminal and the other end is fed from the output of the reference input buffer. Monotonicity is maintained by use of the resistor strings. Linearity depends upon the matching of the resistor elements and upon the performance of the output buffer. Because the inputs are buffered, the DACs always present a high-impedance load to the reference sources. There are two input reference terminals; REF1 is used for DACA through DACD and REF2 is used by DACE through DACH.

Each DAC output is buffered by a configurable-gain output amplifier, which can be programmed to times 1 or times 2 gain.

On powerup, the DACs are reset to CODE 0.

Each output voltage is given by:

$$V_O(\text{DACA|BIC|DIE|FIG|IH}) = \text{REF} \times \frac{\text{CODE}}{256} \times (1 + \text{RNG bit value})$$

where CODE is in the range 0 to 255 and the range (RNG) bit is a 0 or 1 within the serial-control word.

data interface

With LOAD high, data is clocked into the DATA terminal on each falling edge of CLK. Once all data bits have been clocked in, LOAD is pulsed low to transfer the data from the serial-input register to the selected DAC as shown in Figure 1. If LDAC is low, the selected DAC output voltage is updated and LOAD goes low. If LDAC is high during serial programming, the new value is stored within the device and can be transferred to the DAC output at a later time by pulsing LDAC low as shown in Figure 2. Data is entered MSB first.

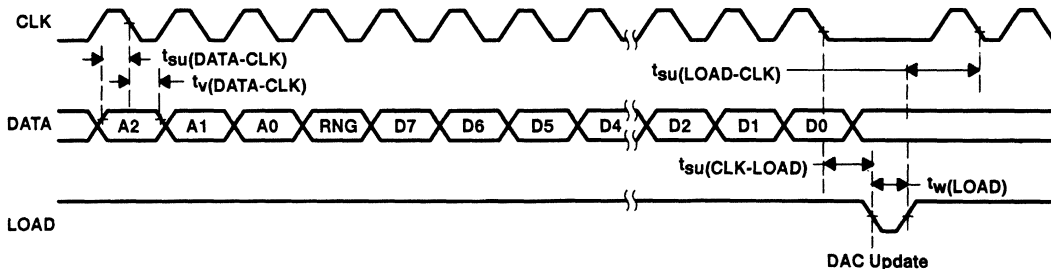


Figure 1. LOAD-Controlled Update (LDAC = Low)

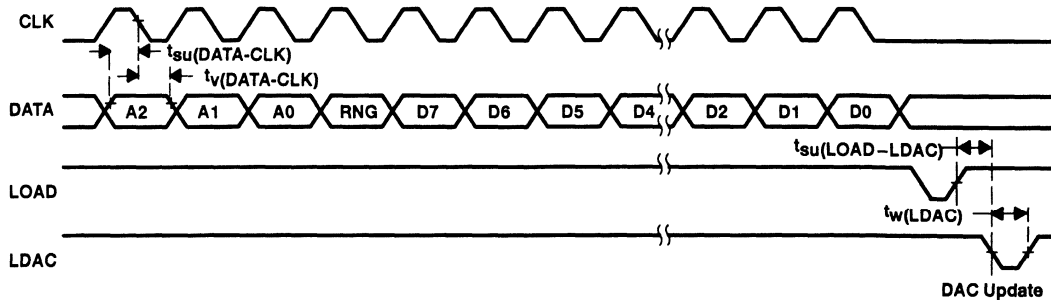


Figure 2. LDAC-Controlled Update

PRODUCT PREVIEW

TLV5628C, TLV5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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data interface (continued)

Table 1 lists the A1 and A0 bits and the selection of the updated DACs. The RNG bit controls the DAC output range. When RNG = low, the output range is between the applied reference voltage and GND, and when RNG = high, the range is between twice the applied reference voltage and GND.

Table 1. Serial-Input Decode

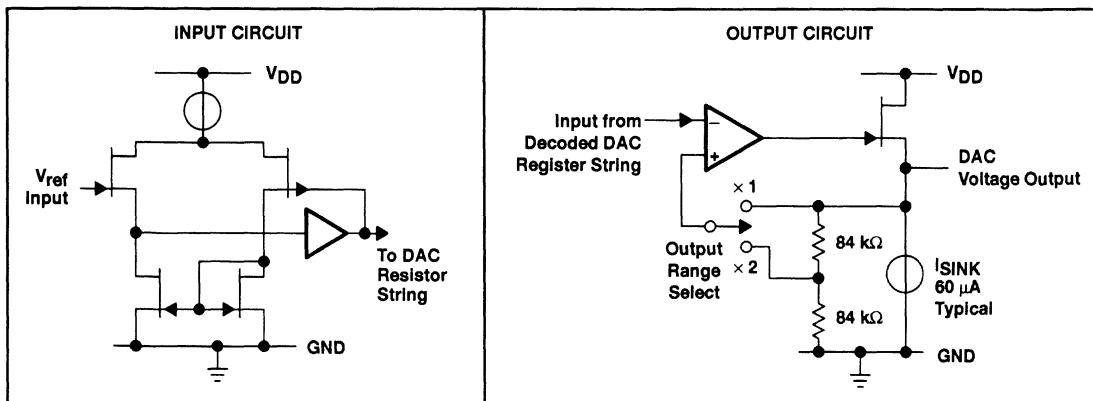
A2	A1	A0	DAC UPDATED
0	0	0	DACA
0	0	1	DACB
0	1	0	DACC
0	1	1	DACD
1	0	0	DACE
1	0	1	DACF
1	1	0	DACG
1	1	1	DACH

Table 2. Ideal-Output Transfer

D7	D6	D5	D4	D3	D2	D1	D0	OUTPUT VOLTAGE
0	0	0	0	0	0	0	0	GND
0	0	0	0	0	0	0	1	$(1/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
0	1	1	1	1	1	1	1	$(127/256) \times \text{REF} (1+\text{RNG})$
1	0	0	0	0	0	0	0	$(128/256) \times \text{REF} (1+\text{RNG})$
•	•	•	•	•	•	•	•	•
•	•	•	•	•	•	•	•	•
1	1	1	1	1	1	1	1	$(255/256) \times \text{REF} (1+\text{RNG})$

PRODUCT PREVIEW

equivalent inputs and outputs



TLV5628C, TLV5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage ($V_{DD} - GND$)	7 V
Digital input voltage range, V_{ID}	GND – 0.3 V to $V_{DD} + 0.3$ V
Reference input voltage range	GND – 0.3 V to $V_{DD} + 0.3$ V
Operating free-air temperature range, T_A : TLV5628C	0°C to 70°C
TLV5628I	–40°C to 85°C
Storage temperature range, T_{stg}	–50°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	230°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD}	2.7	3.3	5.25	V
High-level digital input voltage, V_{IH}	0.8 V_{DD}			V
Low-level digital input voltage, V_{IL}	0.8			V
Reference voltage, V_{ref} [AIBICIDIEIFIGIH], X1 gain	$V_{DD}-0.5$			V
Load resistance, R_L	10			k Ω
Setup time, data input, $t_{su}(DATA-CLK)$ (see Figures 1 and 2)	50			ns
Valid time, data input valid after $CLK\downarrow$, $t_v(DATA-CLK)$ (see Figures 1 and 2)	50			ns
Setup time, CLK eleventh falling edge to $LOAD$, $t_{su}(CLK-LOAD)$ (see Figure 1)	50			ns
Setup time, $LOAD\uparrow$ to $CLK\downarrow$, $t_{su}(LOAD-CLK)$ (see Figure 1)	50			ns
Pulse duration, $LOAD$, $t_w(LOAD)$ (see Figure 1)	250			ns
Pulse duration, $LDAC$, $t_w(LDAC)$ (see Figure 2)	250			ns
Setup time, $LOAD\uparrow$ to $LDAC\downarrow$, $t_{su}(LOAD-LDAC)$ (see Figure 2)	0			ns
CLK frequency	1			MHz
Operating free-air temperature, T_A	TLV5628C		70	°C
	TLV5628I		85	°C

PRODUCT PREVIEW



TLV5628C, TLV5628I OCTAL 8-BIT DIGITAL-TO-ANALOG CONVERTERS

SLAS108 – JANUARY 1995

**electrical characteristics over recommended operating free-air temperature range,
V_{DD} = 3 V to 3.6 V, V_{ref} = 2 V, × 1 gain output range (unless otherwise noted)**

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I _{IH}	High-level digital input current	V _I = V _{DD}			±10	μA
I _{IL}	Low-level digital input current	V _I = 0 V			±10	μA
I _{O(sink)}	Output sink current	Each DAC output	20			μA
I _{O(source)}	Output source current		1			mA
C _i	Input capacitance			15		pF
	Reference input capacitance			15		
I _{DD}	Supply current	V _{DD} = 3.3 V			4	mA
I _{ref}	Reference input current	V _{DD} = 3.3 V, V _{ref} = 1.5 V			±10	μA
E _L	Linearity error (end point corrected)	V _{ref} = 1.25 V, × 2 gain (see Note 1)			±1	LSB
E _D	Differential-linearity error	V _{ref} = 1.25 V, × 2 gain (see Note 2)			±0.9	LSB
E _{ZS}	Zero-scale error	V _{ref} = 1.25 V, × 2 gain (see Note 3)	0		30	mV
	Zero-scale error temperature coefficient	V _{ref} = 1.25 V, × 2 gain (see Note 4)		10		μV/°C
E _{FS}	Full-scale error	V _{ref} = 1.25 V, × 2 gain (see Note 5)			±60	mV
	Full-scale error temperature coefficient	V _{ref} = 1.25 V, × 2 gain (see Note 6)		±25		μV/°C
PSRR	Power-supply sensitivity	See Notes 7 and 8		0.5		mV/V

- NOTES: 1. Integral nonlinearity (INL) is the maximum deviation of the output from the line between zero-scale and full scale (excluding the effects of zero code and full-scale errors).
2. Differential nonlinearity (DNL) is the difference between the measured and ideal 1 LSB amplitude change of any two adjacent codes. Monotonic means the output voltage changes in the same direction (or remains constant) as a change in the digital input code.
3. Zero-scale error is the deviation from zero voltage output when the digital input code is zero.
4. Zero-scale error temperature coefficient is given by: ZSETC = [ZSE(T_{max}) - ZSE(T_{min})]/V_{ref} × 10⁶/(T_{max} - T_{min}).
5. Full-scale error is the deviation from the ideal full-scale output (V_{ref} - 1 LSB) with an output load of 10 kΩ.
6. Full-scale temperature coefficient is given by: FSETC = [FSE(T_{max}) - FSE(T_{min})]/V_{ref} × 10⁶/(T_{max} - T_{min}).
7. Zero-scale error rejection ratio (ZSE-RR) is measured by varying the V_{DD} voltage from 4.5 V to 5.5 V dc and measuring the proportion of this signal imposed on the zero-code output voltage.
8. Full-scale error rejection ratio (FSE-RR) is measured by varying the V_{DD} from 3.0 V to 3.6 V dc and measuring the proportion of this signal imposed on the full-scale output voltage.

**operating characteristics over recommended operating free-air temperature range,
V_{DD} = 3 V to 3.6 V, V_{ref} = 2 V, × 1 gain output range (unless otherwise noted)**

	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Output slew rate	C _L = 100 pF, R _L = 10 kΩ		1		V/μs
Output settling time	To 0.5 LSB, C _L = 100 pF, R _L = 10 kΩ, See Note 9		10		μs
Large-signal bandwidth	Measured at -3 dB point		100		kHz
Digital crosstalk	CLK = 1-MHz square wave measured at DACA-DACH		-50		dB
Reference feedthrough	See Note 10		-60		dB
Channel-to-channel isolation	See Note 11		-60		dB
Reference input bandwidth	See Note 12		100		kHz

- NOTES: 9. Settling time is the time for the output signal to remain within ±0.5 LSB of the final measured value for a digital input code change of 00 hex to FF hex or FF hex to 00 hex. For TLC5628C: V_{DD} = 5 V, V_{ref} = 2 V and range = ×2. For TLC5628I: V_{DD} = 3 V, V_{ref} = 1.25 V and range = ×2.
10. Reference feedthrough is measured at any DAC output with an input code = 00 hex with a V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
11. Channel-to-channel isolation is measured by setting the input code of one DAC to FF hex and the code of all other DACs to 00 hex with V_{ref} input = 1 V dc + 1 V_{pp} at 10 kHz.
12. Reference bandwidth is the -3 dB bandwidth with an input at V_{ref} = 1.25 V dc + 2 V_{pp}, with a digital input code of full-scale.

PRODUCT PREVIEW



PARAMETER MEASUREMENT INFORMATION

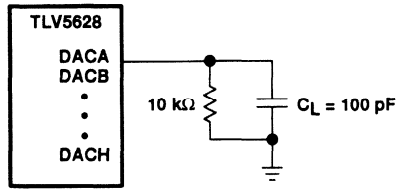
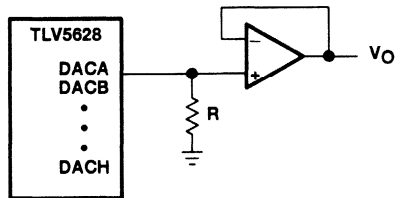


Figure 3. Slewing Settling Time and Linearity Measurements

APPLICATION INFORMATION



NOTE A: Resistor R ≥ 10 kΩ

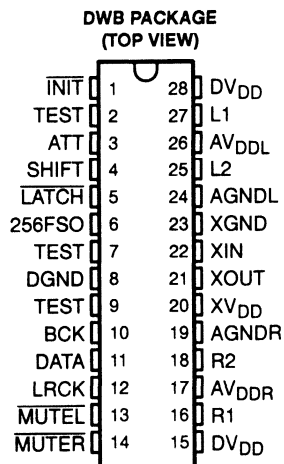
Figure 4. Output Buffering Schemes

PRODUCT PREVIEW

TMS57014A DUAL AUDIO DIGITAL-TO-ANALOG CONVERTER

SLAS077C – SEPTEMBER 1993 – REVISED JUNE 1995

- Single 5-V Power Supply
- Sample Rates (F_s) up to 48 kHz
- 18-Bit Resolution
- Pulse-Width-Modulation (PWM) Output
- Deemphasis Filter for Sample Rates of 32, 37.8, 44.1, and 48 kHz
- Mute With Zero-Data-Detect Flags
- Digital Attenuation to -60 dB
- Total Harmonic Distortion of 0.004% Maximum
- Total-Channel Dynamic Range of 96 dB Minimum
- Serial-Port Interface
- Differential Architecture
- CMOS Technology
- 2s-Complement Data Format



description

The TMS57014A is a stereo, oversampled sigma-delta, digital-to-analog converter (DAC) designed for use in systems such as compact disks, digital audio tapes, multimedia, and video cassette recorders. The device provides high-resolution signal conversion. This device consists of two identical synchronous conversion paths for left and right audio channels. Other overhead functions provide on-chip timing and control.

Additional features include muting, attenuation, deemphasis, and zero-data detection. Control words (16-bit) from a host controller or processor implement these functions.

The TMS57014A is characterized for operation from 0°C to 70°C.

AVAILABLE OPTION†

T_A	PACKAGE
	SMALL OUTLINE (DWB)
0°C to 70°C	TMS57014ADWBLE

† Available on tape and reel (LE) only.



This device contains circuits to protect its inputs and outputs against damage due to high static voltages or electrostatic fields; however, it is advised that precautions be taken to avoid application of any voltage higher than maximum-rated voltages to these high-impedance circuits. During storage or handling, the device leads should be shorted together or the device should be placed in conductive foam. In a circuit, unused inputs should always be connected to an appropriated logic voltage level, preferably either V_{CC} or ground.

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

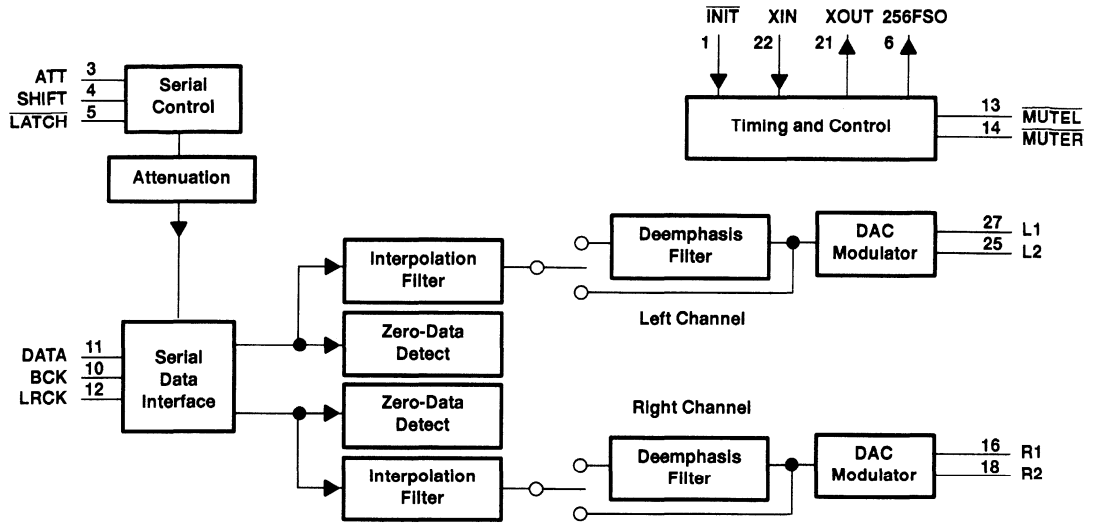
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functional block diagram



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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ATT	3	I	Serial control data. ATT is a 16-bit word configured as LSB first (see Tables 2, 3, and 4).
AVDDL	26	I	Analog power supply (left channel)
AVDDR	17	I	Analog power supply (right channel)
AGNDL	24	I	Analog ground (left channel)
AGNDR	19	I	Analog ground (right channel)
BCK	10	I	Bit clock input. The shift clock signal clocks serial audio data into the device.
DATA	11	I	Audio data input. DATA can be configured as 16 or 18 bits with MSB or LSB first. DATA is 2s complement.
DVDD	15, 28	I	Digital supply
DGND	8	I	Digital ground
$\overline{\text{INIT}}$	1	I	Reset. When $\overline{\text{INIT}}$ is brought low, the device is reset. The device is activated on the rising edge of $\overline{\text{INIT}}$. The LRCK signal must be applied to the device for a reset to occur.
LATCH	5	I	Serial-control data latch. Control data loads into the internal registers when LATCH is brought low.
LRCK	12	I	Left/right clock. LRCK signifies whether the serial data is associated with the left-channel DAC (when high) or the right-channel DAC (when low).
MUTEL	13	O	Left-channel mute flag active. When the left channel is mute or the data through the channel remains at zero for the system-register selected time, MUTEL is brought low.
$\overline{\text{MUTER}}$	14	O	Right-channel mute flag active. When the right channel is mute or the data through the channel remains at zero for the system-register selected time, $\overline{\text{MUTER}}$ is brought low.
L1	27	O	Left PWM output 1
L2	25	O	Left PWM output 2
R1	16	O	Right PWM output 1
R2	18	O	Right PWM output 2
SHIFT	4	I	Shift clock. SHIFT clocks the control data into the internal registers.
TEST	2, 7, 9	I	All TEST inputs should be tied low.
XIN	22	I	Master clock in. XIN derives all the key logic signals of the device. XIN runs at $512F_s$, where F_s is the sample rate.
XOUT	21	O	Master clock out
XVDD	20	I	Power supply for clock section
XGND	23	I	Ground for clock section
256FSO	6	O	System clock out. 256FSO reflects the master clock input divided by 2. The rate is $256F_s$, where F_s is the sample rate.

detailed description

The TMS57014A incorporates an interpolation FIR filter and oversampled modulator. The pulse-width-modulation (PWM) digital output feeds into an external low-pass filter to recover the analog audio signal.

Two control registers configure the device, the attenuation register controls the attenuation range and the system register controls additional functions (see register set section).

reset/initialization

When $\overline{\text{INIT}}$ is brought low, an internal reset signal becomes active approximately 120 cycles of the sampling frequency (F_s) after the falling edge of $\overline{\text{INIT}}$. Under this condition, all internal circuits are initialized and the PWM output is held at zero data (50% duty cycle). When $\overline{\text{INIT}}$ is brought high, the internal reset signal goes inactive for a maximum of five LRCK periods after the rising edge of $\overline{\text{INIT}}$. At this point, internal clocks are synchronous with LRCK and the PWM output is valid (see Figure 1). The LRCK signal must be applied for proper initialization.



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reset/initialization (continued)

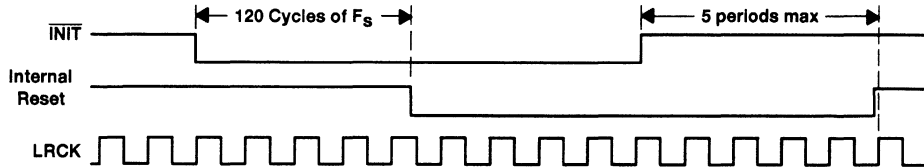


Figure 1. Reset Timing Relationships

timing and control

The timing and control circuit generates and distributes necessary clocks throughout this design. XIN is the external master clock input. The sample rate of the data paths is set as $LRCK = XIN/512$. With a fixed oversampling ratio of 32x and each PWM output value requiring 16 XIN cycles, the effect of changing XIN is shown in Table 1.

The DAC can be operated at any conversion rate between 48 kHz and 32 kHz by choosing the appropriate master-clock frequency. Some of the functions of the converter, such as the deemphasis filter, operate only at the frequencies in Table 1.

Table 1. Master Clock to Sample Rate Comparison

XIN (MHz)	256FSO (MHz)	LRCK (kHz)
24.5760	12.2880	48.0
22.5792	11.2896	44.1
19.3536	9.6768	37.8
16.3840	8.1920	32.0

digital audio data interface

The conversion cycle is synchronized to the rising edge of LRCK, and the data must meet the setup requirements specified in the timing requirements table. The input data is 16 or 18 bits with the MSB or LSB first as selected in the system register. The BCK frequency must be equal to or greater than $32 F_s$ for 16-bit data or $36 F_s$ for 18-bit data where F_s is the sample rate. Figure 2 illustrates the input timing.

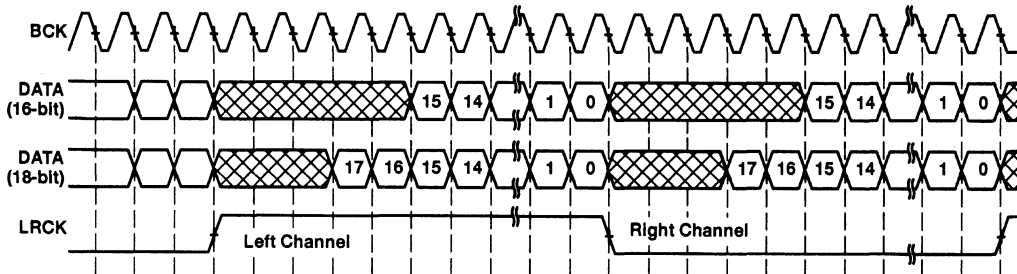


Figure 2. Audio-Data Input Timing

serial-control interface

This device uses the most-significant-bit-first format. Therefore, for a 16-bit word, D15 is the most significant bit and D0 is the least significant bit. Unless otherwise specified, all values are in 2s-complement format.

serial-control-data input

The 16-bit control-data input implements the device-control functions. The TMS57014A has two registers for this data: the system register and the attenuation register. The system register contains most of the system configuration information, and the attenuation register controls audio output level, deemphasis, and mute. Figure 3 illustrates the input timing for ATT, SHIFT, and LATCH. The data loads internally on the falling edge of LATCH. The shift clock should be high for the LATCH setup time before LATCH goes low.

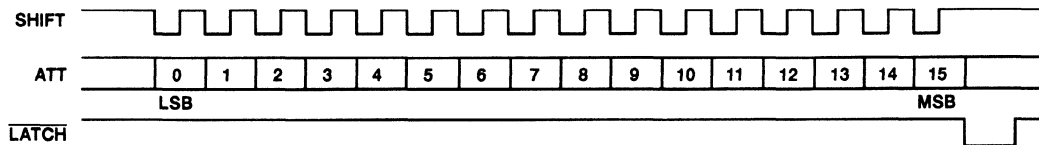


Figure 3. Control-Data-Input Timing

mute

When mute is activated, the output PWM becomes zero data (50% duty cycle). The two mute flags, $\overline{\text{MUTEL}}$ and $\overline{\text{MUTER}}$, are independently set low based on the data in the respective channel being zero. This function becomes active under the following conditions:

1. When the zero-data detector detects that the input data has been zero for 2500 cycles of F_s or 12500 cycles of F_s (as selected in the control registers), output is 50% duty cycle.
2. When the MUTE register value is set high by means of the serial-control data.
3. When $\overline{\text{INIT}}$ is active (low), output is 50% duty cycle.

zero-data detect

After the input data remains zero for 2500 or 12500 cycles of F_s as set by the system register (D4, D5), the channel-mute flag becomes active. Zero-data detection is available for both channels independently, so the two outputs ($\overline{\text{MUTER}}$ and $\overline{\text{MUTEL}}$) indicate that zero data has been detected on the respective channel. The zero-detect register value in the serial-control data selects the detection period. The mute flag returns high immediately when nonzero input data is received.

deemphasis filter

Four sets of deemphasis-filter coefficients support four sampling rates (F_s): 32, 37.8, 44.1, and 48 kHz. Internal register values select the filter coefficients. The internal register values enable or disable the filter. Figure 4 illustrates the deemphasis characteristics.

Many audio sources have been recorded with preemphasis characteristics that are the inverse of the deemphasis characteristics shown in Figure 4. This device provides reconstruction of the original frequency response.

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deemphasis filter (continued)

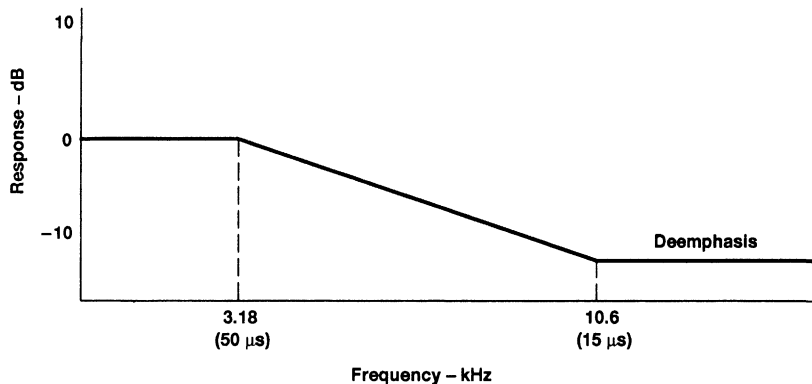


Figure 4. Deemphasis Characteristics

digital attenuation

A value selected in the internal attenuation register determines the attenuation of the digital-audio-data input. The attenuation value is 11 bits long with a valid range of hex values from 400h to 000h. A data value of 001h corresponds to an attenuation value of -60 dB and a data value of 400h corresponds to 0 dB. The attenuation function is nonlinear (see equation 1). Figure 5 demonstrates the attenuation function in dB. The default attenuation value is 400h.

$$\text{Attenuation} = 20 \log \left(\frac{\text{attenuation data}}{1024} \right) \quad (1)$$

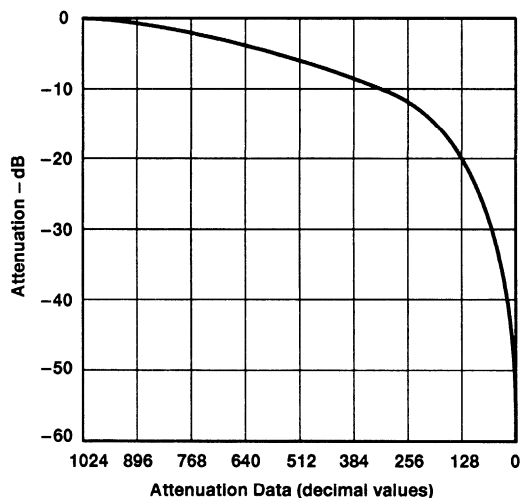


Figure 5. Digital Attenuation Characteristics

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register set

Table 2 contains the register-set selection. Tables 3 and 4 list the bit functions.

Table 2. Register-Set Selection

BITS		DESCRIPTION
15	14	
0	0	Attenuation register
0	1	System register
1	x	Invalid condition†

† Bit 15 should always be set to 0 when writing data for proper operation.

Table 3. Attenuation-Register Bit Functions

BITS				FUNCTION
13	12	11	10–0	
0	—	—	—	Deemphasis off
1	—	—	—	Deemphasis on
—	0	—	—	Channel mute off
—	1	—	—	Channel mute on
—	—	0	—	Bit 11 must be low
—	—	—	0	Digital attenuation, mute
—	—	—	1	Digital attenuation, –60.2 dB
—	—	—	2	Digital attenuation, –54.2 dB
—	—	—	3	Digital attenuation, –50.7 dB
—	—	—	...	
—	—	—	1FF	Digital attenuation, –6.04 dB
—	—	—	200	Digital attenuation, –6.02 dB
—	—	—	201	Digital attenuation, –6.00 dB
—	—	—	...	
—	—	—	3FF	Digital attenuation, –0.01 dB
—	—	—	400	Digital attenuation, 0.00 dB

default 0400h

NOTE: The attenuation values shown are typical values. Refer to the digital attenuation section for a description of the attenuation function.

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Table 4. System-Register Bit Functions

BITS								FUNCTION
13	12	11–6	5	4	3–2	1	0	
0	—	—	—	—	—	—	—	MSB first, audio data
1	—	—	—	—	—	—	—	LSB first, audio data
—	0	—	—	—	—	—	—	16-bit, audio data
—	1	—	—	—	—	—	—	18-bit, audio data
—	—	0	—	—	—	—	—	Bits 11–6 must be low
—	—	—	0	—	—	—	—	Zero data detect period (2500 cycles of F_S)
—	—	—	1	—	—	—	—	Zero data detect period (12500 cycles of F_S)
—	—	—	—	0	—	—	—	Bit 4 must be low
—	—	—	—	—	0	—	—	Deemphasis – 44.1 kHz
—	—	—	—	—	1	—	—	Deemphasis – 48.0 kHz
—	—	—	—	—	2	—	—	Deemphasis – 37.8 kHz
—	—	—	—	—	3	—	—	Deemphasis – 32.0 kHz
—	—	—	—	—	—	0	—	LRCK and PWM are not synchronized
—	—	—	—	—	—	1	—	LRCK and PWM synchronized
—	—	—	—	—	—	—	0	Bit 0 must be low

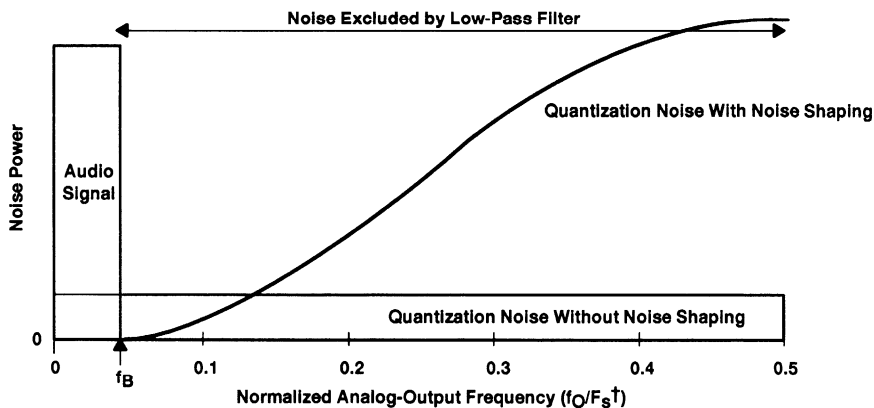
Default = 0000h

Interpolation filter

The interpolation filter used prior to the DAC increases the digital data rate from the LRCK speed to the oversampled rate by interpolating with a ratio of 1:32. The oversampling modulator receives the output of this filter with deemphasis as an option.

DAC modulator

The DAC is a 3rd-order modulator with 32 times oversampling. The DAC provides high-resolution, low-noise performance using a 15-value PWM output as shown in Figure 6.



† f_0 is the output frequency at the low-pass filter output (V_O) shown in Figure 10.

Figure 6. Oversampling Noise Power With and Without Noise Shaping

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PWM output (L2–L1 and R2–R1)

The L2–L1 and the R2–R1 output pairs are pulse-width-modulated (PWM) signals with the L2–L1 differential pulse duration determining the left-channel analog voltage and the R2–R1 differential pulse duration determining the right-channel analog voltage.

Each DAC left and right output consists of 15 levels of PWM and provides a differential signal as the input to two external differential amplifiers configured as a low-pass filter to produce the left and right audio outputs (see Figure 9).

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Analog supply voltage range, AV _{DDL} , AV _{DDR} (see Note 1)	–0.3 V to 7 V
Digital supply voltage range, DV _{DD} (see Note 2)	–0.3 V to 7 V
Clock supply voltage range, XV _{DD} (see Note 3)	–0.3 V to 7 V
Output voltage range, V _O :	
L1, L2	–0.3 V to AV _{DDL} + 0.3 V
R1, R2	–0.3 V to AV _{DDR} + 0.3 V
Input voltage range, V _I	–0.3 V to DV _{DD} + 0.3 V
Operating free-air temperature range, T _A	0°C to 70°C
Case temperature for 10 seconds, T _C	260°C
Storage temperature range, T _{stg}	–55°C to 150°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values for maximum ratings are with respect to AGNDL and AGNDR respectively.
 2. Voltage values for maximum ratings are with respect to DGND.
 3. Voltage values for maximum ratings are with respect to XGND.

recommended operating conditions (see Note 4)

	MIN	NOM	MAX	UNIT
Analog supply voltage, AV _{DDL} , AV _{DDR}	4.75	5	5.25	V
Digital supply voltage, DV _{DD}	4.75	5	5.25	V
Clock supply voltage, XV _{DD}	4.75	5	5.25	V
High-level input voltage, V _{IH}	XIN			V
	All other digital inputs			
Low-level input voltage, V _{IL}	XIN			V
	All other digital inputs			
Load resistance at PWM, R _L	10			kΩ
Master clock frequency at XIN	16.3		24.6	MHz
Operating free-air temperature, T _A	0		70	°C

NOTE 4: DV_{DD}, AV_{DDL}, XV_{DD} and AV_{DDR} tied together represents V_{DD}.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

digital interface, $AV_{DD} = DV_{DD} = 5 V \pm 5\%$ (see Note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	256FSO			V _{DD} -0.5	V
		L1, L2, R1, R2	I _O = -12 mA		V _{DD} -0.5	
		XOUT	I _O = -1.2 mA		V _{DD} -0.5	
		MUTEL, MUTER	I _O = -1 mA		V _{DD} -0.5	
V _{OL}	Low-level output voltage	256FSO	I _O = 0.4 mA		0.4	V
		L1, L2, R1, R2	I _O = 12 mA		0.5	
		XOUT	I _O = 1.2 mA		0.5	
		MUTEL, MUTER	I _O = 1 mA		0.4	
I _{IH}	High-level input current, any digital input			±1	±5	μA
I _{IL}	Low-level input current, any digital input			±1	±5	μA
C _i	Input capacitance			5		pF
C _o	Output capacitance			5		pF

† All typical values are at T_A = 25°C.

NOTE 4: DV_{DD}, AV_{DDL}, XV_{DD} and AV_{DDR} tied together represents V_{DD}.

supplies, $AV_{DD} = DV_{DD} = 5 V \pm 5\%$, no load

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Analog power supply current	AV _{DDL} and AV _{DDR} are shorted together		15		mA
Digital power supply current			15		mA
Total device supply current over operating temperature range				60	mA
Power dissipation				350	mW

† All typical values are at T_A = 25°C.

DAC modulator, $AV_{DD} = DV_{DD} = 5 V \pm 5\%$, sample rate (F_s) = 44.1 kHz, full-scale input sine wave at 1 kHz, T_A = 25°C, bandwidth is 20 Hz to 20 kHz

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Resolution	See Note 5	18			bits
Signal-to-noise ratio	A-weighted, 20 Hz to 20 kHz, See Figure 10, Table 5, and Note 5	96	100		dB
Total harmonic distortion	20 Hz to 20 kHz, See Note 5			0.003%	

† All typical values are at T_A = 25°C.

NOTE 5: These specifications are measured at the output (V_O) of the low-pass filter shown in Figure 9.

filter characteristics, $AV_{DD} = DV_{DD} = 5 V \pm 5\%$, deemphasis disabled

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Pass-band ripple	Sample rate (F _s) = 48 kHz, See Note 5	-0.002		0.002	dB
Stop-band attenuation		75			dB
Pass band (-3 dB) (DAC)	See Note 5	0		0.46 F _s	kHz
Stop band		0.54 F _s			kHz
Group delay		29/F _s			s

† All typical values are at T_A = 25°C.

NOTE 5: These specifications are measured at the output (V_O) of the low-pass filter shown in Figure 7.



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timing requirements (see Figures 8 and 9 and Note 6)

		MIN	MAX	UNIT
t_{w1}	Pulse duration, BCK	160		ns
t_{su1}	Setup time, DATA before BCK↑	20		ns
t_{h1}	Hold time, DATA after BCK↑	20		ns
t_{su2}	Setup time, LRCK before BCK↑	50		ns
t_{h2}	Hold time, LRCK after BCK↑	50		ns
t_{w2}	Pulse duration, SHIFT	100		ns
t_{su3}	Setup time, ATT before SHIFT↑	20		ns
t_{h3}	Hold time, ATT after SHIFT↑	20		ns
t_{w3}	Pulse duration, LATCH	100		ns
t_{su4}	Setup time, LATCH before SHIFT↑	100		ns
t_{h4}	Hold time, LATCH after SHIFT↑	$t_{w2} + 20$		ns

NOTE 6: All timing measurements were taken at the $V_{DD}/2$ voltage level.

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PARAMETER MEASUREMENT INFORMATION

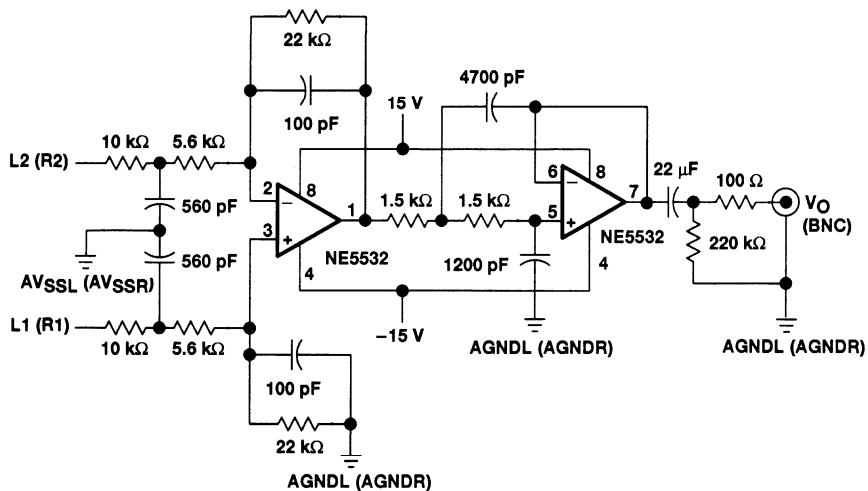


Figure 7. Analog Low-Pass Filter Recommended for Measuring the Dynamic Specifications of the TMS57014A

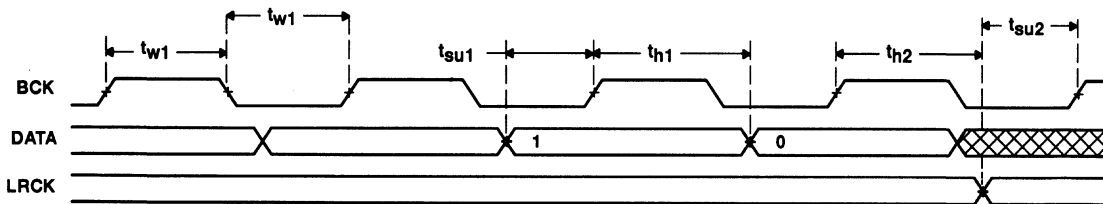


Figure 8. Audio-Data Serial Timing

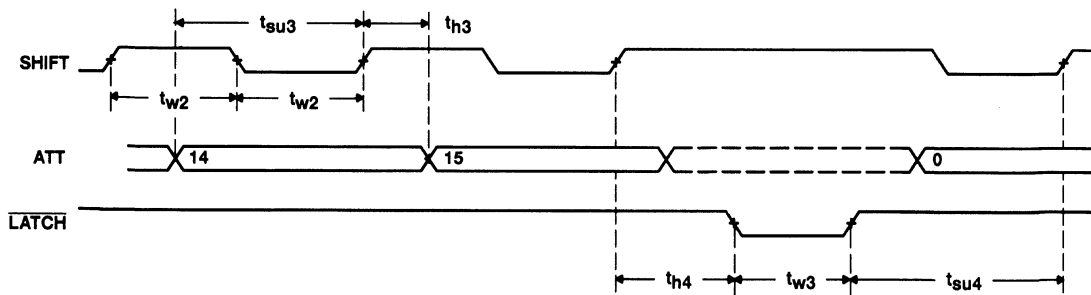


Figure 9. Control-Data Serial Timing

PARAMETER MEASUREMENT INFORMATION

Table 5. A-Weighted Data

FREQUENCY	A WEIGHTING (dB)	FREQUENCY	A WEIGHTING (dB)
25	-44.6 ± 2	800	-0.1 ± 1
31.5	-39.2 ± 2	1000	0 ± 0
40	-34.5 ± 2	1250	0.6 ± 1
50	-30.2 ± 2	1600	1.0 ± 1
63	-26.1 ± 2	2000	1.2 ± 1
80	-22.3 ± 2	2500	1.2 ± 1
100	-19.1 ± 1	3150	1.2 ± 1
125	-16.1 ± 1	4000	1.0 ± 1
160	-13.2 ± 1	5000	0.5 ± 1
200	-10.8 ± 1	6300	-0.1 ± 1
250	-8.6 ± 1	8000	-1.1 ± 1
315	-6.5 ± 1	10000	-2.4 ± 1
400	-4.8 ± 1	12500	-4.2 ± 2
500	-3.2 ± 1	16000	-6.5 ± 2
630	-1.9 ± 1		

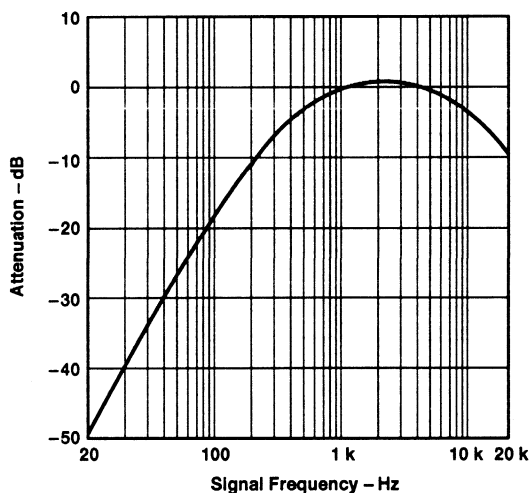


Figure 10. A-Weighted Function

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APPLICATION INFORMATION

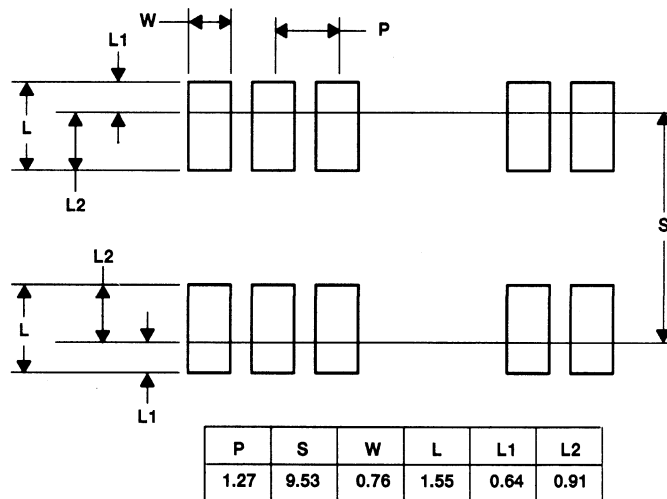
circuit and layout considerations

The designer should follow these guidelines for the best device performance.

- Separate digital and analog ground planes should be used. All digital device functions should be over the digital ground plane, and all analog device functions should be over the analog ground plane. The ground planes should be connected at only one point to the direct power supply, and this is usually at the connector edge of the board.
- A single crystal-controlled clock should synchronously generate all digital signals
- All power supply lines should include a 0.1- μF and a 1- μF capacitor. If clock noise is excessive, a toroidal inductance of 10 μH should be placed in series with XV_{DD} before connecting to DV_{DD} .
- The digital input control signals should be buffered if they are generated off the card.
- Clock jitter should be minimized, and precautions taken to prevent clock overshoot. This minimizes any high-frequency coupling to the analog output.

PCB footprint

Figure 11 shows the printed-circuit-board (PCB) land pattern for the TMS57014A small-outline package.



NOTE A: All linear dimensions are in millimeters.

Figure 11. Land Pattern for PCB Layout

AD7524M

Advanced LinCMOS™ 8-BIT MULTIPLYING DIGITAL-TO-ANALOG CONVERTER

SGLS028A – SEPTEMBER 1989 – REVISED MARCH 1995

- **Advanced LinCMOS™ Silicon-Gate Technology**
- **Easily Interfaced to Microprocessors**
- **On-Chip Data Latches**
- **Monotonicity Over Entire A/D Conversion Range**
- **Segmented High-Order Bits Ensure Low-Glitch Output**
- **Designed to Be Interchangeable With Analog Devices AD7524, PMI PM-7524, and Micro Power Systems MP7524**
- **Fast Control Signaling for Digital Signal Processor Applications Including Interface With SMJ320**

KEY PERFORMANCE SPECIFICATIONS	
Resolution	8 Bits
Linearity error	1/2 LSB Max
Power dissipation at $V_{DD} = 5\text{ V}$	5 mW Max
Settling time	100 ns Max
Propagation delay	80 ns Max

description

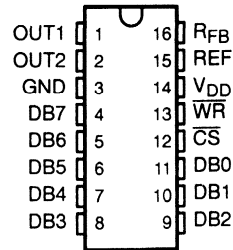
The AD7524M is an Advanced LinCMOS™ 8-bit digital-to-analog converter (DAC) designed for easy interface to most popular microprocessors.

The AD7524M is an 8-bit multiplying DAC with input latches and with a load cycle similar to the write cycle of a random access memory. Segmenting the high-order bits minimizes glitches during changes in the most-significant bits, which produce the highest glitch impulse. The AD7524M provides accuracy to 1/2 LSB without the need for thin-film resistors or laser trimming, while dissipating less than 5 mW typically.

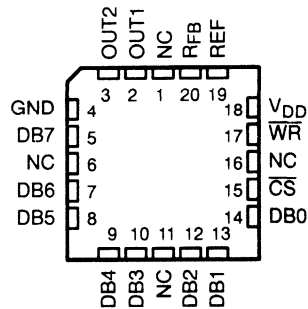
Featuring operation from a 5-V to 15-V single supply, the AD7524M interfaces easily to most microprocessor buses or output ports. Excellent multiplying (2 or 4 quadrant) makes the AD7524M an ideal choice for many microprocessor-controlled gain-setting and signal-control applications.

The AD7524M is characterized for operation from -55°C to 125°C .

**J PACKAGE
(TOP VIEW)**



**FK PACKAGE
(TOP VIEW)**



NC—No internal connection

AVAILABLE OPTIONS

T_A	PACKAGE	
	CERAMIC CHIP CARRIER (FK)	CERAMIC DIP (J)
-55°C to 125°C	AD7524MFK	AD7524MJ

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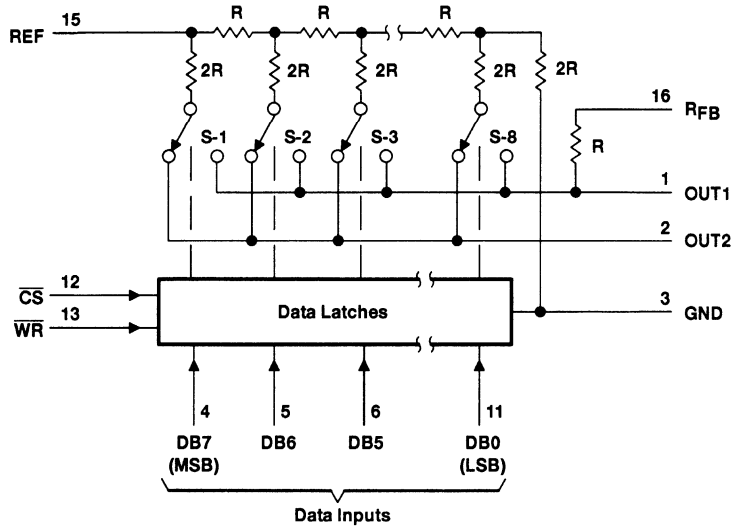


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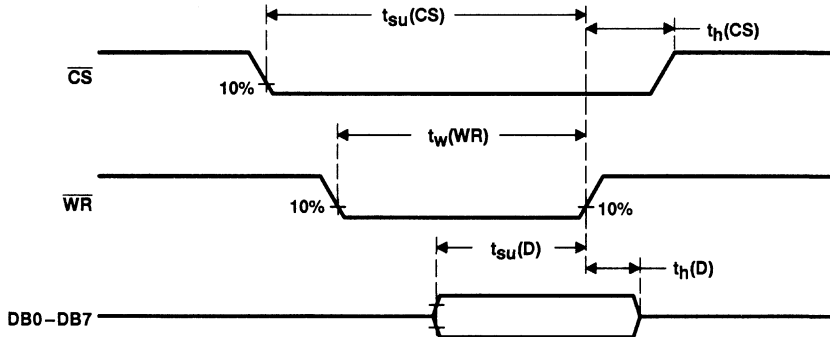
AD7524M
Advanced LinCMOS™ 8-BIT MULTIPLYING
DIGITAL-TO-ANALOG CONVERTER

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functional block diagram



operating sequence



AD7524M
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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{DD}	–0.3 V to 17 V
Voltage between R_{FB} and GND	±25 V
Digital input voltage range, V_I	–0.3 V to $V_{DD}+0.3$ V
Reference voltage range, V_{ref}	±25 V
Peak digital input current, I_I	10 μ A
Operating free-air temperature range, T_A	–55°C to 125°C
Storage temperature range, T_{stg}	–65°C to 150°C
Case temperature for 60 seconds, T_C : FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package	300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

recommended operating conditions

	$V_{DD} = 5$ V			$V_{DD} = 15$ V			UNIT
	MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{DD}	4.75	5	5.25	14.5	15	15.5	V
Reference voltage, V_{ref}	±10			±10			V
High-level input voltage, V_{IH}	2.4			13.5			V
Low-level input voltage, V_{IL}	0.8			1.5			V
\overline{CS} setup time, $t_{su}(CS)$	40			40			ns
\overline{CS} hold time, $t_h(CS)$	0			0			ns
Data bus input setup time, $t_{su}(D)$	25			25			ns
Data bus input hold time, $t_h(D)$	10			10			ns
Pulse duration, \overline{WR} low, $t_w(WR)$	40			40			ns
Operating free-air temperature, T_A	–55		125	–55		125	°C



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electrical characteristics over recommended operating free-air temperature range, $V_{ref} = 10\text{ V}$,
OUT1 and OUT2 at GND (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V _{DD} = 5 V			V _{DD} = 15 V			UNIT		
				MIN	TYP	MAX	MIN	TYP	MAX			
I _{IH}	High-level input current	V _I = V _{DD}	Full-range	10			10			μA		
			25°C	1			1					
I _{IL}	Low-level input current	V _I = 0	Full-range	-10			-10			μA		
			25°C	-1			-1					
I _{pkg}	Output leakage current	OUT1	DB0–DB7 at 0, \overline{WR} and \overline{CS} at 0 V	Full-range	±400			±200			nA	
			V _{ref} = ±10 V	25°C	±50			±50				
		OUT2	DB0–DB7 at V _{DD} , \overline{WR} and \overline{CS} at 0	Full-range	±400			±200				
			V _{ref} = ±10 V	25°C	±50			±50				
I _{DD}	Supply current	Quiescent	DB0–DB7 at V _{IHmin} or V _{ILmax}			2			2			mA
			Standby	DB0–DB7 at 0 V or V _{DD}			Full-range	500			500	
						25°C	100			100		
k _{SVS}	Supply voltage sensitivity, $\Delta\text{gain}/\Delta V_{DD}$	$\Delta V_{DD} = 10\%$	Full-range	0.16			0.04			%/%		
			25°C	0.002 0.02			0.001 0.02					
C _i	Input capacitance, DB0–DB7, \overline{WR} , \overline{CS}	V _I = 0	5			5			pF			
C _o	Output capacitance	OUT1	DB0–DB7 at 0, \overline{WR} and \overline{CS} at 0 V			30			30			pF
			OUT2	120			120					
		OUT2	DB0–DB7 at V _{DD} , \overline{WR} and \overline{CS} at 0 V			120			120			
			OUT1	30			30					
Reference input impedance (REF to GND)			5	20			5	20			kΩ	

operating characteristics over recommended operating free-air temperature range, $V_{ref} = 10\text{ V}$,
OUT1 and OUT2 at GND (unless otherwise noted)

PARAMETER		TEST CONDITIONS		V _{CC} = 5 V		V _{DD} = 15 V		UNIT
				MIN	MAX	MIN	MAX	
Linearity error				±0.2		±0.2		%FSR
Gain error	See Note 1	Full range	±1.4		±0.6		%FSR	
		25°C	±1		±0.5			
Settling time (to 1/2 LSB)		See Note 2		100		100		ns
Propagation delay from digital input to 90% of final analog output current		See Note 2		80		80		ns
Feedthrough at OUT1 or OUT2	V _{ref} = ±10 V (100 kHz sinewave), \overline{WR} and \overline{CS} at 0, DB0–DB7 at 0	Full range	0.5		0.5		%FSR	
		25°C	0.25		0.25			
Temperature coefficient of gain		T _A = 25°C to t _{min} or t _{max}		±0.004		±0.001		%FSR/°C

NOTES: 1. Gain error is measured using the internal feedback resistor. Nominal Full Scale Range (FSR) = $V_{ref} - 1\text{ LSB}$.

2. OUT1 load = 100 Ω, C_{ext} = 13 pF, \overline{WR} at 0 V, \overline{CS} at 0 V, DB0–DB7 at 0 V to V_{DD} or V_{DD} to 0 V.



PRINCIPLES OF OPERATION

The AD7524M is an 8-bit multiplying D/A converter consisting of an inverted R-2R ladder, analog switches, and data input latches. Binary weighted currents are switched between the OUT1 and OUT2 bus lines, thus maintaining a constant current in each ladder leg independent of the switch state. The high-order bits are decoded and these decoded bits, through a modification in the R-2R ladder, control three equally weighted current sources. Most applications only require the addition of an external operational amplifier and a voltage reference.

The equivalent circuit for all digital inputs low is seen in Figure 1. With all digital inputs low, the entire reference current, I_{ref} , is switched to OUT2. The current source $1/256$ represents the constant current flowing through the termination resistor of the R-2R ladder, while the current source I_{lkg} represents leakage currents to the substrate. The capacitances appearing at OUT1 and OUT2 are dependent upon the digital input code. With all digital inputs high, the off-state switch capacitance (30 pF maximum) appears at OUT2 and the on-state switch capacitance (120 pF maximum) appears at OUT1. With all digital inputs low, the situation is reversed as shown in Figure 1. Analysis of the circuit for all digital inputs high is similar to Figure 1; however, in this case, I_{ref} would be switched to OUT1.

Interfacing the AD7524M D/A converter to a microprocessor is accomplished via the data bus and the \overline{CS} and \overline{WR} control signals. When \overline{CS} and \overline{WR} are both low, the AD7524M analog output responds to the data activity on the DB0–DB7 data bus inputs. In this mode, the input latches are transparent and input data directly affects the analog output. When either the CS signal or WR signal goes high, the data on the DB0–DB7 inputs are latched until the \overline{CS} and \overline{WR} signals go low again. When \overline{CS} is high, the data inputs are disabled regardless of the state of the \overline{WR} signal.

The AD7524M is capable of performing 2-quadrant or full 4-quadrant multiplication. Circuit configurations for 2-quadrant or 4-quadrant multiplication are shown in Figures 2 and 3. Input coding for unipolar and bipolar operation are summarized in Tables 1 and 2, respectively.

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PRINCIPLES OF OPERATION

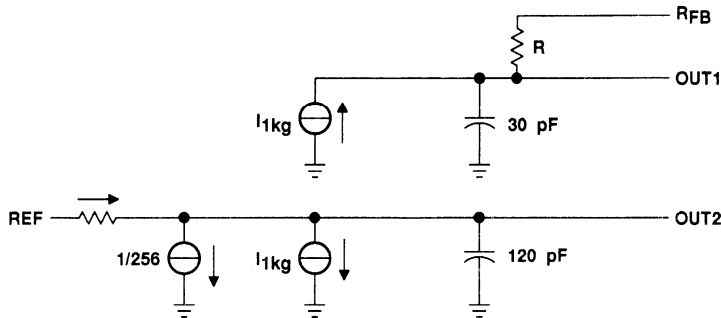


Figure 1. AD7524M Equivalent Circuit With All Digital Inputs Low

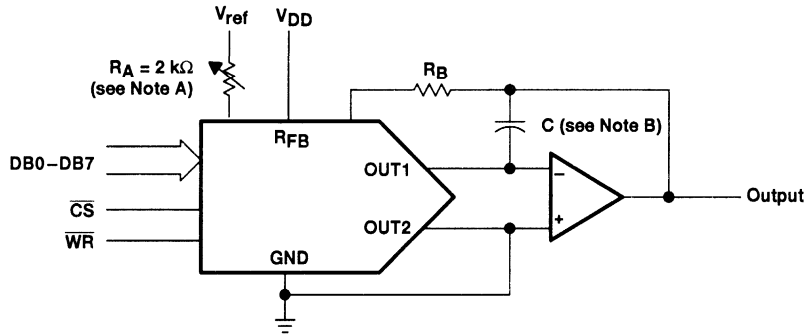


Figure 2. Unipolar Operation (2-Quadrant Multiplication)

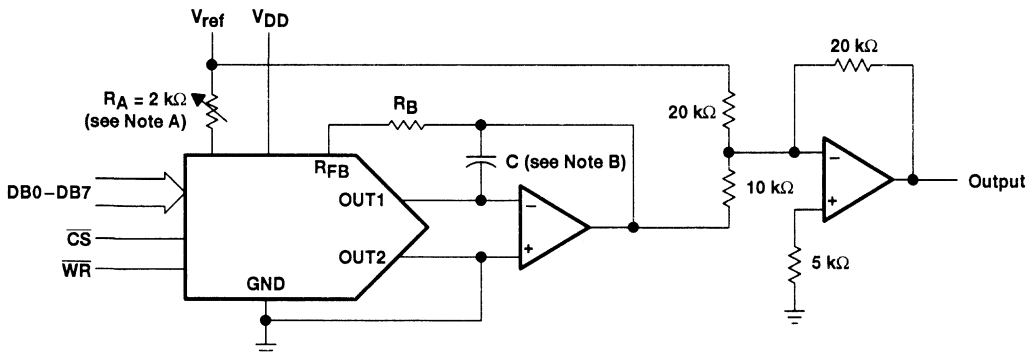


Figure 3. Bipolar Operation (4-Quadrant Operation)

NOTES: A. R_A and R_B used only if gain adjustment is required.
 B. C phase compensation (10 – 15 pF) is required when using high-speed amplifiers to prevent ringing or oscillation.



PRINCIPLES OF OPERATION

Table 1. Unipolar Binary Code

DIGITAL INPUT (SEE NOTE 3)		ANALOG OUTPUT
MSB	LSB	
11111111		$-V_{ref} (255/256)$
10000001		$-V_{ref} (129/256)$
10000000		$-V_{ref} (128/256) = -V_{ref} / 2$
01111111		$-V_{ref} (127/256)$
00000001		$-V_{ref} (1/256)$
00000000		0

Table 2. Bipolar (Offset Binary) Code

DIGITAL INPUT (SEE NOTE 4)		ANALOG OUTPUT
MSB	LSB	
11111111		$V_{ref} (127/128)$
10000001		$V_{ref} (128)$
10000000		0
01111111		$-V_{ref} (128)$
00000001		$-V_{ref} (127/128)$
00000000		$-V_{ref}$

NOTES: 3. LSB = $1/256 (V_{ref})$.
 4. LSB = $1/128 (V_{ref})$.

microprocessor interfaces

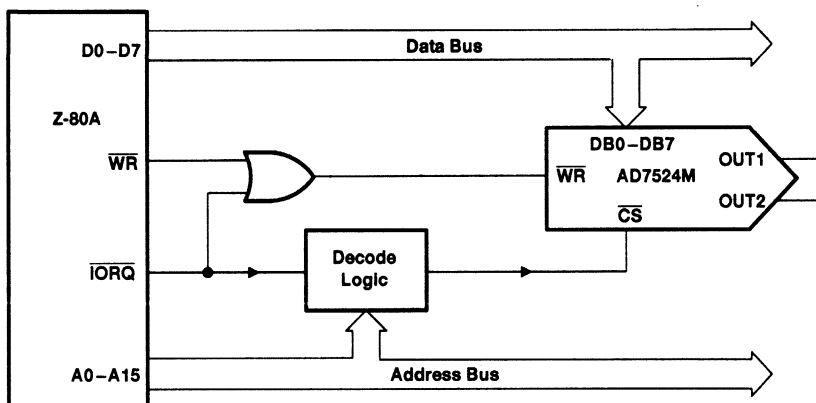


Figure 4. AD7524M-Z-80A Interface

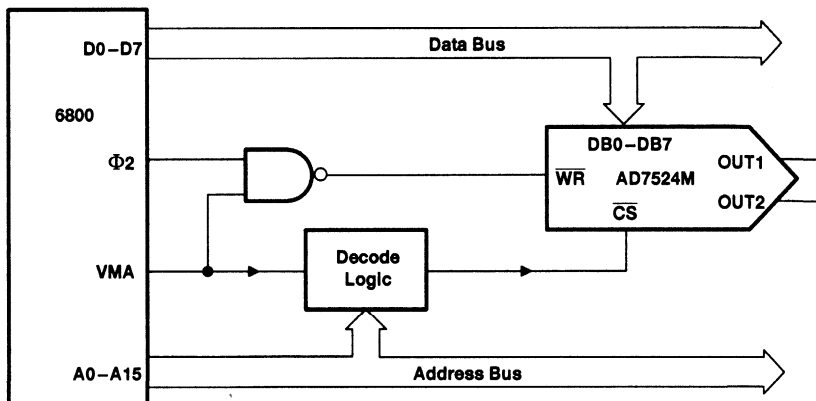


Figure 5. AD7524M-6800 Interface

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microprocessor interfaces (continued)

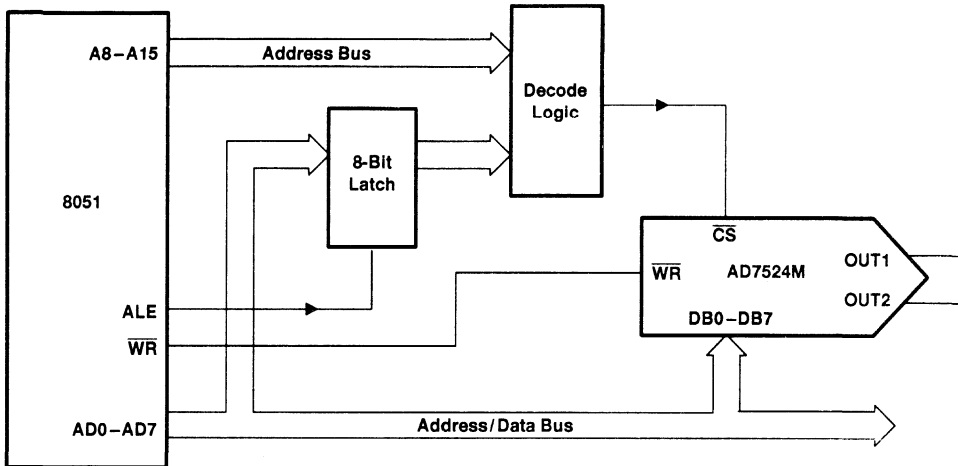


Figure 6. AD7524M-8051 Interface

General Information	1
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Special Functions	5
Video Interface Palettes	6
Data Manuals	7
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4

DSP Analog Interface and Conversion

TLC32040C, TLC32040I, TLC32041C, TLC32041I ANALOG INTERFACE CIRCUITS

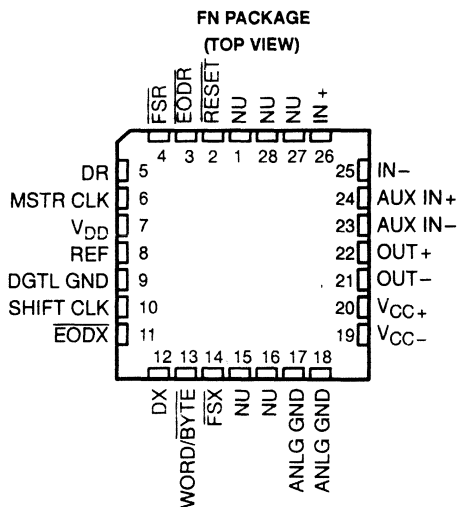
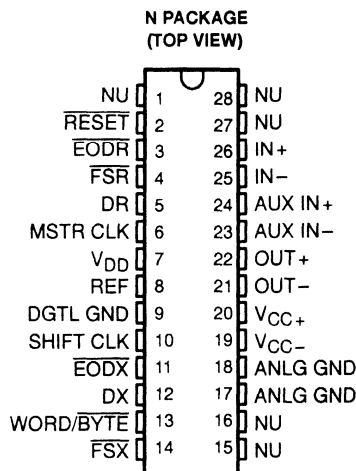
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- 14-Bit Dynamic Range ADC and DAC
- Variable ADC and DAC Sampling Rate Up to 19,200 Samples per Second
- Switched-Capacitor Antialiasing Input Filter and Output-Reconstruction Filter
- Serial Port for Direct Interface to TMS32011, TMS320C17, TMS32020, and TMS320C25 Digital Signal Process
- Synchronous or Asynchronous ADC and DAC Conversion Rate With Programmable Incremental ADC and DAC Conversion Timing Adjustments
- Serial Port Interface to SN74299 Serial-to-Parallel Shift Register for Parallel Interface to TMS32010, TMS320C15, or Other Digital Processors
- 600-Mil Wide N Package (C_L to C_L)
- 2s Complement Format
- CMOS Technology

PART NUMBER	DESCRIPTION
TLC32040	Analog interface circuit with internal reference. Also a plug-in replacement for TLC32041.
TLC32041	Analog interface circuit without internal reference

description

The TLC32040 and TLC32041 are complete analog-to-digital and digital-to-analog input/output systems, each on a single monolithic CMOS chip. This device integrates a bandpass switched-capacitor antialiasing input filter, a 14-bit-resolution A/D converter, four microprocessor-compatible serial port modes, a 14-bit-resolution D/A converter, and a low-pass switched-capacitor output-reconstruction filter.



NU – Nonusable; no external connection should be made to these terminals.

AVAILABLE OPTIONS

T _A	PACKAGE	
	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC32040CFN TLC32041CFN	TLC32040CN TLC32041CN
-40°C to 85°C		TLC32040IN TLC32041IN

TLC32040C, TLC32040I, TLC32041C, TLC32041I

ANALOG INTERFACE CIRCUITS

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description (continued)

The device offers numerous combinations of master clock input frequencies and conversion/sampling rates, which can be changed via digital processor control.

Typical applications for this integrated circuit include modems (7.2-, 8-, 9.6-, 14.4-, and 19.2-kHz sampling rate), analog interface for digital signal processors (DSPs), speech recognition/storage systems, industrial process control, biomedical instrumentation, acoustical signal processing, spectral analysis, data acquisition, and instrumentation recorders. Four serial modes, which allow direct interface to the TMS32011, TMS320C17, TMS32020, and TMS320C25 digital signal processors, are provided. Also, when the transmit and receive sections of the analog interface circuit (AIC) are operating synchronously, it can interface to two SN74299 serial-to-parallel shift registers. These serial-to-parallel shift registers can then interface in parallel to the TMS32010, TMS320C15, other digital signal processors, or external FIFO circuitry. Output data pulses are emitted to inform the processor that data transmission is complete or to allow the DSP to differentiate between two transmitted bytes. A flexible control scheme is provided so that the functions of this integrated circuit can be selected and adjusted coincidentally with signal processing via software control.

The antialiasing input filter comprises seventh-order and fourth-order CC-type (Chebyshev/elliptic transitional) low-pass and high-pass filters, respectively and a fourth-order equalizer. The input filter is implemented in switched-capacitor technology and is preceded by a continuous time filter to eliminate any possibility of aliasing caused by sampled data filtering. When no filtering is desired, the entire composite filter can be switched out of the signal path. A selectable, auxiliary, differential analog input is provided for applications where more than one analog input is required.

The A/D and D/A converters each have 14 bits of resolution. The A/D and D/A architectures ensure no missing codes and monotonic operation. An internal voltage reference is provided on the TLC32040 to ease the design task and to provide complete control over the performance of this integrated circuit. The internal voltage reference is brought out to a terminal and is available to the designer. Separate analog and digital voltage supplies and grounds are provided to minimize noise and ensure a wide dynamic range. Also, the analog circuit path contains only differential circuitry to keep noise to an absolute minimum. The only exception is the DAC sample and hold, which utilizes pseudo-differential circuitry.

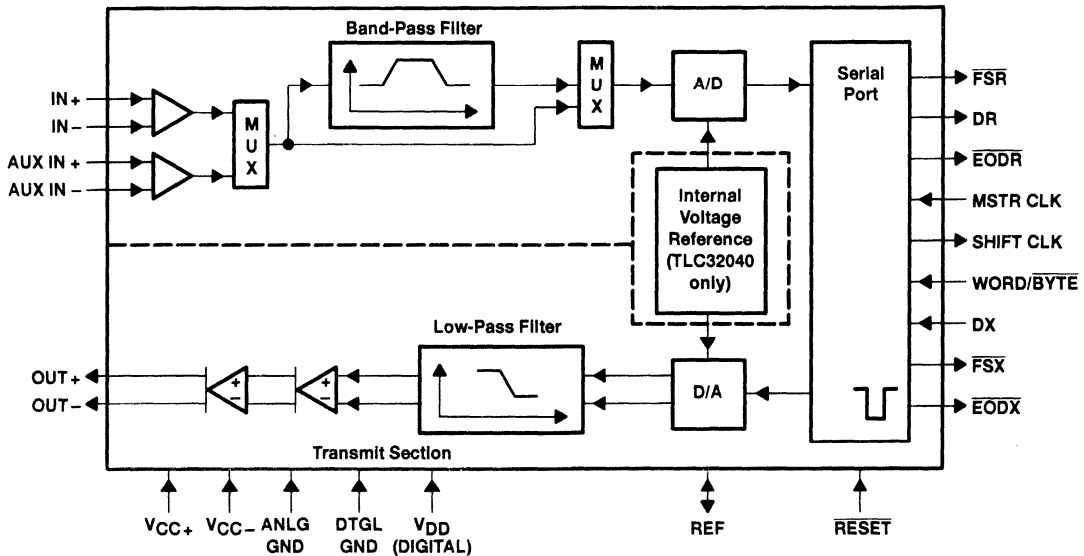
The output-reconstruction filter is a seventh-order CC-type (Chebyshev/elliptic transitional low-pass filter followed by a fourth-order equalizer) and is implemented in switched-capacitor technology. This filter is followed by a continuous-time filter to eliminate images of the digitally encoded signal.

The TLC32040C and TLC32041C are characterized for operation from 0°C to 70°C, and the TLC32040I and TLC32041I are characterized for operation from -40°C to 85°C.

TLC32040C, TLC32040I, TLC32041C, TLC32041I ANALOG INTERFACE CIRCUITS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANLG GND	17,18		Analog ground return for all internal analog circuits. Not internally connected to DTGL GND.
AUX IN+	24	I	Noninverting auxiliary analog input state. This input can be switched into the bandpass filter and A/D converter path via software control. If the appropriate bit in the control register is a 1, the auxiliary inputs replace the IN+ and IN- inputs. If the bit is a 0, the IN+ and IN- inputs are used (see the AIC DX data word format section).
AUX IN-	23	I	Inverting auxiliary analog input (see the above AUX IN+ description)
DTGL GND	9		Digital ground for all internal logic circuits. Not internally connected to ANLG GND.
DR	5	O	DR is used to transmit the ADC output bits from the AIC to the TMS320 serial port. This transmission of bits from the AIC to the TMS320 serial port is synchronized with the SHIFT CLK signal.
DX	12	I	DX is used to receive the DAC input bits and timing and control information from the TMS320. This serial transmission from the TMS320 serial port to the AIC is synchronized with the SHIFT CLK signal.
EODR	3	O	End of data receive. See the WORD/BYTE description and the Serial Port Timing diagrams. During the word-mode timing, EODR is a low-going pulse that occurs immediately after the 16 bits of A/D information have been transmitted from the AIC to the TMS320 serial port. EODR can be used to interrupt a microprocessor upon completion of serial communications. Also, EODR can be used to strobe and enable external serial-to-parallel shift registers, latches, or external FIFO RAM, and to facilitate parallel data bus communications between the AIC and the serial-to-parallel shift registers. During the byte-mode timing, EODR goes low after the first byte has been transmitted from the AIC to the TMS320 serial port and is kept low until the second byte has been transmitted. The TMS32011 or TMS320C17 can use this low-going signal to differentiate between the two bytes as to which is first and which is second. EODR does not occur after secondary communication.

TLC32040C, TLC32040I, TLC32041C, TLC32041I

ANALOG INTERFACE CIRCUITS

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Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
EODX	11	O	End of data transmit. See the WORD/BYTE description and the Serial Port Timing diagram. During the word-mode timing, EODX is a low-going pulse that occurs immediately after the 16 bits of D/A converter and control or register information have been transmitted from the TMS320 serial port to the AIC. EODX can be used to interrupt a microprocessor upon the completion of serial communications. Also, EODX can be used to strobe and enable external serial-to-parallel shift registers, latches, or an external FIFO RAM, and to facilitate parallel data-bus communications between the AIC and the serial-to-parallel shift registers. During the byte-mode timing, EODX goes low after the first byte has been transmitted from the TMS320 serial port to the AIC and is kept low until the second byte has been transmitted. The TMS32011 or TMS320C17 can use this low-going signal to differentiate between the two bytes as to which is first and which is second.
FSR	4	O	Frame sync receive. In the serial transmission modes, which are described in the WORD/BYTE description, FSR is held low during bit transmission. When FSR goes low, the TMS320 serial port begins receiving bits from the AIC via DR of the AIC. The most significant DR bit is present on DR before FSR goes low. (See Serial Port Timing and Internal Timing Configuration diagrams.) FSR does not occur after secondary communication.
FSX	14	O	Frame sync transmit. When FSX goes low, the TMS320 serial port begins transmitting bits to the AIC via DX of the AIC. In all serial transmission modes, which are described in the WORD/BYTE description, FSX is held low during bit transmission (see the Serial Port Timing and Internal Timing Configuration diagrams).
IN+	26	I	Noninverting input to analog input amplifier stage
IN-	25	I	Inverting input to analog input amplifier stage
MSTR CLK	6	I	Master clock. MSTR CLK is used to derive all the key logic signals of the AIC, such as the shift clock, the switched-capacitor filter clocks, and the A/D and D/A timing signals. The Internal Timing Configuration diagram shows how these key signals are derived. The frequencies of these key signals are synchronous submultiples of the master clock frequency to eliminate unwanted aliasing when the sampled analog signals are transferred between the switched-capacitor filters and the A/D and D/A converters (see the Internal Timing Configuration).
OUT+	22	O	Noninverting output of analog output power amplifier. OUT+ can drive transformer hybrids or high-impedance loads directly in either a differential or a single-ended configuration.
OUT-	21	O	Inverting output of analog output power amplifier. OUT- is functionally identical with and complementary to OUT+.
REF	8	I/O	Internal voltage reference for the TLC32040. For the TLC32040 and TLC32041 an external voltage reference can be applied to this terminal.
RESET	2	I	Reset. A reset function is provided to initialize the TA, TA', TB, RA, RA', RB, and control registers. This reset function initiates serial communications between the AIC and DSP. The reset function initializes all AIC registers including the control register. After a negative-going pulse on RESET, the AIC registers are initialized to provide an 8-kHz data conversion rate for a 5.184-MHz master clock input signal. The conversion rate adjust registers, TA' and RA', are reset to 1. The control register bits are reset as follows (see AIC DX data word format section): d7 = 1, d6 = 1, d5 = 1, d4 = 0, d3 = 0, d2 = 1 This initialization allows normal serial-port communication to occur between AIC and DSP.
SHIFT CLK	10	O	Shift clock. SHIFT CLK is obtained by dividing the master clock signal frequency by four. SHIFT CLK is used to clock the serial data transfers of the AIC, described in the WORD/BYTE description below (see the Serial Port Timing and Internal Timing Configuration diagrams).
VDD	7		Digital supply voltage, 5 V ±5%
VCC+	20		Positive analog supply voltage, 5 V ±5%
VCC-	19		Negative analog supply voltage, -5 V ±5%



TLC32040C, TLC32040I, TLC32041C, TLC32041I ANALOG INTERFACE CIRCUITS

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Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
WORD/BYTE	13	I	<p>WORD/BYTE, in conjunction with a bit in the control register, is used to establish one of four serial modes. These four serial modes are described below. <i>AIC transmit and receive sections are operated asynchronously.</i> The following description applies when the AIC is configured to have asynchronous transmit and receive sections. If the appropriate data bit in the control register is a 0 (see the AIC DX data word format section), the transmit and receive sections are asynchronous.</p> <p style="margin-left: 20px;">L Serial port directly interfaces with the serial port of the TMS32011 or TMS320C17 and communicates in two 8-bit bytes. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX or FSR is brought low. One 8-bit byte is transmitted or one 8-bit byte is received. EODX or EODR is brought low. FSX or FSR emits a positive frame-sync pulse that is four shift clock cycles wide. One 8-bit byte is transmitted or one 8-bit byte is received. EODX or EODR is brought high. FSX or FSR is brought high. <p style="margin-left: 20px;">H Serial port directly interfaces with the serial port of the TMS32020, TMS320C25, or TMS320C30 and communicates in one 16-bit word. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX or FSR is brought low. One 16-bit word is transmitted or one 16-bit word is received. FSX or FSR is brought high. EODX or EODR emits a low-going pulse. <p><i>AIC transmit and receive sections are operated synchronously.</i> If the appropriate data bit in the control register is a 1, the transmit and receive sections are configured to be synchronous. In this case, the bandpass switched-capacitor filter and the A/D conversion timing are derived from the TX counter A, TX counter B, and TA, TA', and TB registers, rather than the RX counter A, RX counter B, and RA, RA', and RB registers. In this case, the AIC FSX and FSR timing are identical during primary data communication; however, FSR is not asserted during secondary data communication since there is no new A/D conversion result. The synchronous operation sequences are as follows (see Serial Port Timing diagrams):</p> <p style="margin-left: 20px;">L Serial port directly interfaces with the serial port of the TMS32011 or TMS320C17 and communicates in two 8-bit bytes. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX and FSR are brought low. One 8-bit byte is transmitted and one 8-bit byte is received. EODX and EODR are brought low. FSX and FSR emit positive frame-sync pulses that are four shift clock cycles wide. One 8-bit byte is transmitted and one 8-bit byte is received. EODX and EODR are brought high. FSX and FSR are brought high. <p style="margin-left: 20px;">H Serial port directly interfaces with the serial port of the TMS32020, TMS320C25, or TMS320C30 and communicates in one 16-bit word. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX and FSR are brought low. One 16-bit word is transmitted and one 16-bit word is received. FSX and FSR are brought high. EODX or EODR emit low-going pulses. <p>Since the transmit and receive sections of the AIC are now synchronous, the AIC serial port with additional NOR and AND gates will interface to two SN74299 serial-to-parallel shift registers. Interfacing the AIC to the SN74299 shift register allows the AIC to interface to an external FIFO RAM and facilitates parallel data bus communications between the AIC and the digital signal processor. The operation sequence is the same as the above sequence (see Serial Port Timing diagrams).</p>

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detailed description

analog input

Two sets of analog inputs are provided. Normally, the IN+ and IN– input set is used; however, the auxiliary input set, AUX IN+ and AUX IN–, can be used if a second input is required. Each input set can be operated in either differential or single-ended modes, since sufficient common-mode range and rejection are provided. The gain for the IN+, IN–, AUX IN+, and AUX IN– inputs can be programmed to be either 1, 2, or 4 (see Table 2). Either input circuit can be selected via software control. It is important to note that a wide dynamic range is assured by the differential internal analog architecture and by the separate analog and digital voltage supplies and grounds.

A/D bandpass filter, A/D bandpass filter clocking, and A/D conversion timing

The A/D bandpass filter can be selected or bypassed via software control. The frequency response of this filter is presented in the following pages. This response results when the switched-capacitor filter clock frequency is 288 kHz. Several possible options can be used to attain a 288-kHz switched-capacitor filter clock. When the filter clock frequency is not 288 kHz, the filter transfer function is frequency scaled by the ratio of the actual clock frequency to 288 kHz. The low-frequency roll-off of the high-pass section is 300 Hz.

The internal timing configuration and AIC DX data word format sections of this data sheet indicate the many options for attaining a 288-kHz bandpass switched-capacitor filter clock. These sections indicate that the RX counter A can be programmed to give a 288-kHz bandpass switched-capacitor filter clock for several master clock input frequencies.

The A/D conversion rate is then attained by frequency dividing the 288-kHz bandpass switched-capacitor filter clock with the RX counter B. Thus, unwanted aliasing is prevented because the A/D conversion rate is an integral submultiple of the bandpass switched-capacitor filter sampling rate, and the two rates are synchronously locked.

A/D converter performance specifications

Fundamental performance specifications for the A/D converter circuitry are presented in the A/D converter operating characteristics section of this data sheet. The realization of the A/D converter circuitry with switched-capacitor techniques provides an inherent sample-and-hold.

analog output

The analog output circuitry is an analog output power amplifier. Both noninverting and inverting amplifier outputs are brought out of this integrated circuit. This amplifier can drive transformer hybrids or low-impedance loads directly in either a differential or single-ended configuration.

D/A low-pass filter, D/A low-pass filter clocking, and D/A conversion timing

The frequency response of this filter is presented in the following pages. This response results when the low-pass switched-capacitor filter clock frequency is 288 kHz. Like the A/D filter, the transfer function of this filter is frequency scaled when the clock frequency is not 288 kHz. A continuous-time filter is provided on the output on the output of the D/A low-pass filter to greatly attenuate any switched-capacitor clock feedthrough.

The D/A conversion rate is then attained by frequency dividing the 288-kHz switched-capacitor filter clock with TX counter B. Thus, unwanted aliasing is prevented because the D/A conversion rate is an integral submultiple of the switched-capacitor low-pass filter sampling rate, and the two rates are synchronously locked.

asynchronous versus synchronous operation

If the transmit section of the AIC (low-pass filter and DAC) and receive section (bandpass filter and ADC) are operated asynchronously, the low-pass and band-pass filter clocks are independently generated from the master clock signal. Also, the D/A and A/D conversion rates are independently determined. If the transmit and receive sections are operated synchronously, the low-pass filter clock drives both low-pass and bandpass filters. In synchronous operation, the A/D conversion timing is derived from, and is equal to, the D/A conversion timing. (See description of WORD/BYTE in the Terminal Functions table.)

D/A converter performance specifications

Fundamental performance specifications for the D/A converter circuitry are presented in the D/A converter operating characteristics section of the data sheet. The D/A converter has a sample-and-hold that is realized with a switched-capacitor ladder.

system frequency response correction

The $(\sin x)/x$ correction circuitry is performed in the digital processor software. The system frequency response can be corrected via DSP software to ± 0.1 -dB accuracy to band edge of 3000 Hz for all sampling rates. This correction is accomplished with a first-order digital correction filter, which requires only seven TMS320 instruction cycles. With a 200-ns instruction cycle, seven instructions represent an overhead factor of only 1.1% and 1.3% for sampling rates of 8 and 9.6 kHz, respectively (see the $(\sin x)/x$ correction section for more details).

serial port

The serial port has four possible modes that are described in detail in the Terminal Functions table. These modes are briefly described below and in the description for WORD/BYTE in the Terminal Functions Table.

- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS32011 and TMS320C17.
- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS32020 and the TMS320C25.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS32011 and TMS320C17.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS32020, TMS320C25, or two SN74299 serial-to-parallel shift registers, which can then interface in parallel to the TMS320C10, TMS32015, to any other digital signal processor, or to external FIFO circuitry.

operation of TLC32040 with internal voltage reference

The internal reference of the TLC32040 eliminates the need for an external voltage reference and provides overall circuit cost reduction. Thus, the internal reference eases the design task and provides complete control over the performance of this integrated circuit. The internal reference is brought out to a terminal and is available to the designer. To keep the amount of noise on the reference signal to a minimum, an external capacitor may be connected between REF and ANLG GND.

operation of TLC32040 or TLC32041 with external voltage reference

REF can be driven from an external reference circuit if so desired. This external circuit must be capable of supplying 250 μ A and must be adequately protected from noise such as crosstalk from the analog input.

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reset

A reset function is provided to initiate serial communications between the AIC and DSP and allow fast, cost-effective testing during manufacturing. The reset function initializes all AIC registers, including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC is initialized. This initialization allows normal serial port communications activity to occur between AIC and DSP (see AIC DX data word format section).

loopback

This feature allows the user to test the circuit remotely. In loopback, OUT+ and OUT– are internally connected to IN+ and IN–. Thus, the DAC bits (d15 to d2), which are transmitted to DX, can be compared with the ADC bits (d15 to d2), which are received from DR. An ideal comparison would be that the bits on DR equal the bits on DX. However, in practice there is some difference in these bits due to the ADC and DAC output offsets.

In loopback, if IN+ and N– are enabled, the external signals on IN+ and IN– are ignored. If AUX IN+ and AUX IN– are enabled, the external signals on these terminals are added to the OUT+ and OUT– signals in loopback operation.

The loopback feature is implemented with digital signal processor control by transmitting the appropriate serial port bit to the control register (see AIC DX data word format section).

explanation of internal timing configuration

All of the internal timing of the AIC is derived from the high-frequency clock signal that drives the master clock input. The shift clock signal, which strobes the serial port data between the AIC and DSP, is derived by dividing the master clock input signal frequency by four.

$$\text{SCF Clock Frequency} = \frac{\text{Master Clock Frequency}}{2 \times \text{Contents of Counter A}}$$

$$\text{Conversion Frequency} = \frac{\text{SCF Clock Frequency}}{\text{Contents of Counter B}}$$

$$\text{Shift Clock Frequency} = \frac{\text{Master Clock Frequency}}{4}$$

TX counter A and TX counter B, which are driven by the master clock signal, determine the D/A conversion timing. Similarly, RX counter A and RX counter B determine the A/D conversion timing. In order for the switched-capacitor low-pass and band pass filters to meet their transfer function specifications, the frequency of the clock inputs of the switched-capacitor filters must be 288 kHz. If the frequencies of the clock inputs are not 288 kHz, the filter transfer function frequencies are scaled by the ratios of the clock frequencies to 288 kHz. Thus, to obtain the specified filter responses, the combination of master clock frequency and TX counter A and RX counter A values must yield 288-kHz switched-capacitor clock signals. These 288-kHz clock signals can then be divided by the TX counter B and RX counter B to establish the D/A and A/D conversion timings.

TX counter A and TX counter B are reloaded every D/A conversion period, while RX counter A and RX counter B are reloaded every A/D conversion period. The TX counter B and RX counter B are loaded with the values in the TB and RB registers, respectively. Via software control, the TX counter A can be loaded with either the TA register, the TA register less the TA' register, or the TA register plus the TA' register. By selecting the TA register less the TA' register option, the upcoming conversion timing will occur earlier by an amount of time that equals TA' times the signal period of the master clock. By selecting the TA register plus the TA' register option, the upcoming conversion timing will occur later by an amount of time that equals TA' times the signal period of the master clock. Thus, the D/A conversion timing can be advanced or retarded. An identical ability to alter the A/D conversion timing is provided. In this case, however, the RX counter A can be programmed via software control with the RA register, the RA register less the RA' register, or the RA register plus the RA' register.



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explanation of internal timing configuration (continued)

The ability to advance or retard conversion timing is particularly useful for modem applications. This feature allows controlled changes in the A/D and D/A conversion timing. This feature can be used to enhance signal-to-noise performance, to perform frequency-tracking functions, and to generate nonstandard modem frequencies.

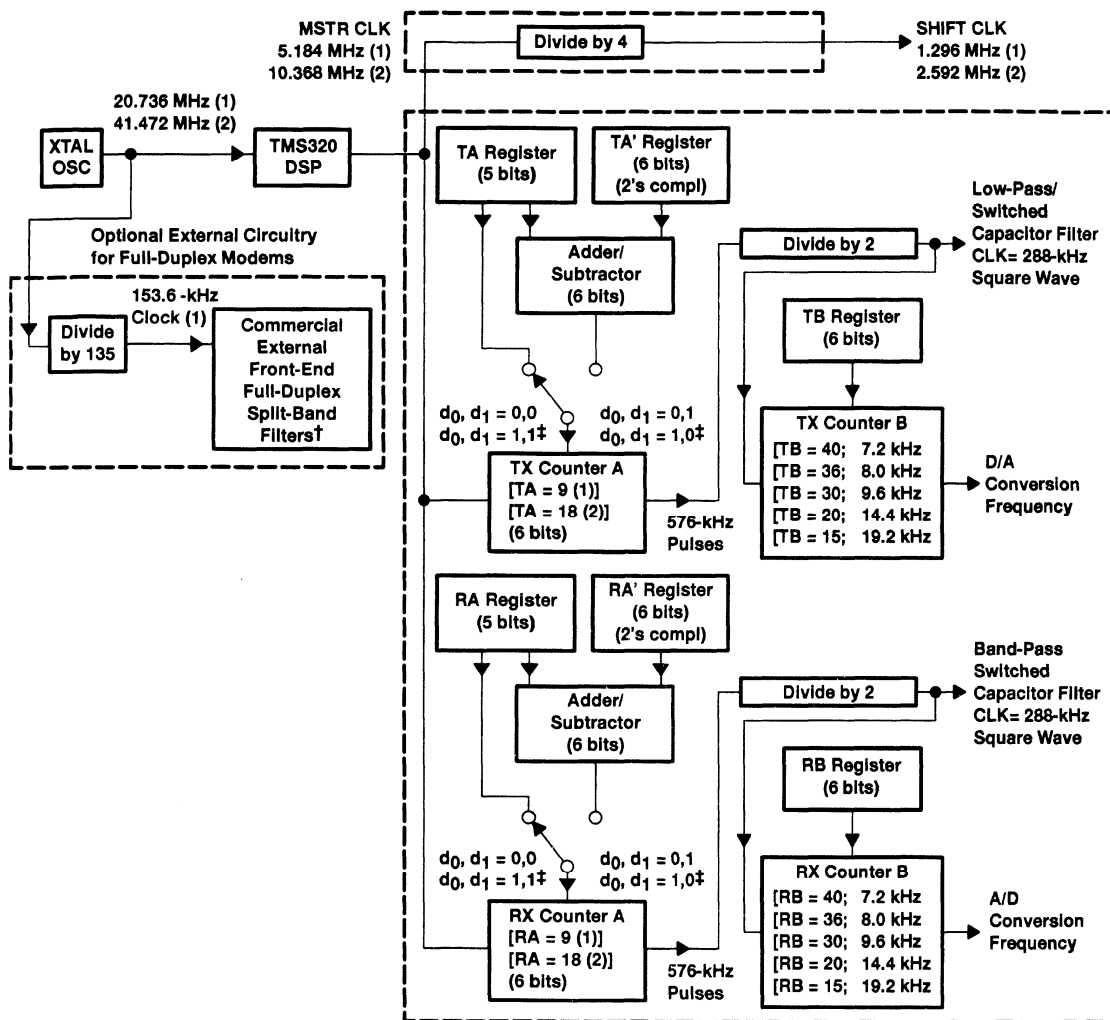
If the transmit and receive sections are configured to be synchronous (see WORD/ $\overline{\text{BYTE}}$ description), then both the low-pass and bandpass switched-capacitor filter clocks are derived from TX counter A. Also, both the D/A and A/D conversion timing are derived from the TX counter A and TX counter B. When the transmit and receive sections are configured to be asynchronous, the RX counter A, RX counter B, RA register, RA' register, and RB registers are not used.



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$$\text{SCF Clock Frequency} = \frac{\text{Master Clock Frequency}}{2 \times \text{Contents of Counter A}}$$

† Split-band filtering can alternatively be performed after the analog input function via software in the TMS320.

‡ These control bits are described in the AIC DX data word format section.

NOTE A: Frequency 1 (20.736 MHz) is used to show how 153.6 kHz (for commercially available modem split-band filter clock), popular speech and modem sampling signal frequencies, and an internal 288-kHz switched-capacitor filter clock can be derived synchronously and as submultiples of the crystal oscillator frequency. Since these derived frequencies are synchronous submultiples of the crystal frequency, aliasing does not occur as the sampled analog signal passes between the analog converter and switched-capacitor filter stages. Frequency 2 (41.472 MHz) is used to show that the AIC can work with high-frequency signals, which are used by high-speed digital signal processors.

Figure 1. Internal Timing Configuration

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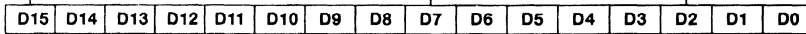
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AIC DR or DX word bit pattern

A/D or D/A MSB,
1st bit sent

1st bit sent of 2nd byte

A/D or D/A LSB



AIC DX data word format section

d15	d14	d13	d12	d11	d10	d9	d8	d7	d6	d5	d4	d3	d2	d1	d0	COMMENTS
primary DX serial communication protocol																
←d15 (MSB) through d2 go to the D/A converter register													→	0	0	The TX and RX counter As are loaded with the TA and RA register values. The TX and RX counter Bs are loaded with TB and RB register values.
←d15 (MSB) through d2 go to the D/A converter register													→	0	1	The TX and RX counter As are loaded with the TA + TA' and RA + RA' register values. The TX and RX counter Bs are loaded with TB and RB register values. Bits d1 = 0 and d0 = 1 cause the next D/A and A/D conversion periods to be changed by the addition of TA' and RA' master clock cycles, in which TA' and RA' can be positive or negative or zero (refer to Table 1).
←d15 (MSB) through d2 go to the D/A converter register													→	1	0	The TX and RX counter As are loaded with the TA – TA' and RA – RA' register values. The TX and RX counter Bs are loaded with TB and RB register values. Bits d1 = 1 and d0 = 0 cause the next D/A and A/D conversion periods to be changed by the subtraction of TA' and RA' master clock cycles, in which TA' and RA' can be positive or negative or zero (refer to Table 1).
←d15 (MSB) through d2 go to the D/A converter register													→	1	1	The TX and RX counter As are loaded with the TA and RA register values. The TX and RX counter Bs are loaded with the TB and RB register values. After a delay of four shift clock cycles, a secondary transmission immediately follows to program the AIC to operate in the desired configuration.

NOTE: Setting the two least significant bits to 1 in the normal transmission of DAC information (primary communications) to the AIC initiates secondary communications upon completion of the primary communications.

Upon completion of the primary communication, \overline{FSX} remains high for four SHIFT CLK cycles and then goes low and initiates the secondary communication. The timing specifications for the primary and secondary communications are identical. In this manner, the secondary communication, if initiated, is interleaved between successive primary communications. This interleaving prevents the secondary communication from interfering with the primary communications and DAC timing, thus preventing the AIC from skipping a DAC output. In the synchronous mode, \overline{FSR} is not asserted during secondary communications.

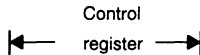


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secondary DX serial communication protocol

x x ← to TA register → x x ← to RA register → 0 0	d13 and d6 are MSBs (unsigned binary)
x ← to TA' register → x ← to RA' register → 0 1	d14 and d7 are 2's complement sign bits
x ← to TB register → x ← to RB register → 1 0	d14 and d7 are MSBs (unsigned binary)
x x x x x x x x d7 d6 d5 d4 d3 d2 1 1	
	d2 = 0/1 deletes/inserts the bandpass filter d3 = 0/1 disables/enables the loopback function d4 = 0/1 disables/enables the AUX IN+ and AUX IN- terminals d5 = 0/1 asynchronous/synchronous transmit receive sections d6 = 0/1 gain control bits (see gain control section) d7 = 0/1 gain control bits (see gain control section)

reset function

A reset function is provided to initiate serial communications between the AIC and DSP. The reset function initializes all AIC registers, including the control register. After power has been applied to the AIC, a negative-going pulse on **RESET** initializes the AIC registers to provide an 8-kHz A/D and D/A conversion rate for a 5.184-MHz master clock input signal. The AIC, except the control register, is initialized as follows (see AIC DX data word format section):

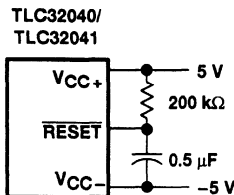
REGISTER	INITIALIZED REGISTER VALUE (HEX)
TA	9
TA'	1
TB	24
RA	9
RA'	1
RB	24

The control register bits are reset as follows (see AIC DX data word format section):

$$d7 = 1, d6 = 1, d5 = 1, d4 = 0, d3 = 0, d2 = 1$$

This initialization allows normal serial port communications to occur between AIC and DSP. If the transmit and receive sections are configured to operate synchronously and the user wishes to program different conversion rates, only the TA, TA', and TB register need to be programmed, since both transmit and receive timing are synchronously derived from these registers (see the terminal descriptions and AIC DX word format sections).

The circuit shown below provides a reset on power up when power is applied in the sequence given under power-up sequence. The circuit depends on the power supplies reaching their recommended values a minimum of 800 ns before the capacitor charges to 0.8 V above DGTL GND.



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power-up sequence

To ensure proper operation of the AIC, and as a safeguard against latch-up, it is recommended that a Schottky diode with a forward voltage less than or equal to 0.4 V be connected from V_{CC-} to ANLG GND (see Figure 17). In the absence of such a diode, power should be applied in the following sequence: ANLG GND and DGTL GND, V_{CC-} , then V_{CC+} and V_{DD} . Also, no input signal should be applied until after power up.

AIC responses to improper conditions

The AIC has provisions for responding to improper conditions. These improper conditions and the response of the AIC to these conditions are presented in Table 1 below.

AIC register constraints

The following constraints are placed on the contents of the AIC registers:

1. TA register must be ≥ 4 in word mode (WORD/BYTE = high).
2. TA register must be ≥ 5 in byte mode (WORD/BYTE = low).
3. TA' register can be either positive, negative, or zero.
4. RA register must be ≥ 4 in word mode (WORD/BYTE = high).
5. RA register must be ≥ 5 in byte mode (WORD/BYTE = low).
6. RA' register can be either positive, negative, or zero.
7. (TA register \pm TA' register) must be > 1 .
8. (RA register \pm RA' register) must be > 1 .
9. TB register must be > 1 .

Table 1. AIC Responses To Improper Conditions

IMPROPER CONDITIONS	AIC RESPONSE
TA register + TA' register = 0 or 1 TA register - TA' register = 0 or 1	Reprogram TX counter A with TA register value
TA register + TA' register < 0	MODULO 64 arithmetic is used to ensure that a positive value is loaded into the TX counter A, i.e., TA register + TA' register + 40 hex is loaded into TX counter A.
RA register + RA' register = 0 or 1 RA register - RA' register = 0 or 1	Reprogram RX counter A with RA register value
RA register + RA' register = 0 or 1	MODULO 64 arithmetic is used to ensure that a positive value is loaded into RX counter A, i.e., RA register + RA' register + 40 hex is loaded into RX counter A.
TA register = 0 or 1 RA register = 0 or 1	The AIC is shut down.
TA register < 4 in word mode TA register < 5 in byte mode RA register < 4 in word mode RA register < 5 in byte mode	The AIC serial port no longer operates.
TB register = 0 or 1	Reprogram TB register with 24 hex
RB register = 0 or 1	Reprogram RB register with 24 hex
AIC and DSP cannot communicate	Hold last DAC output

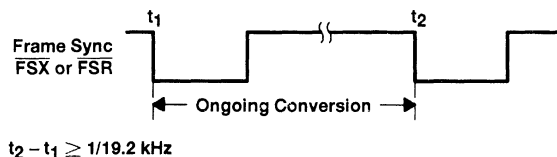
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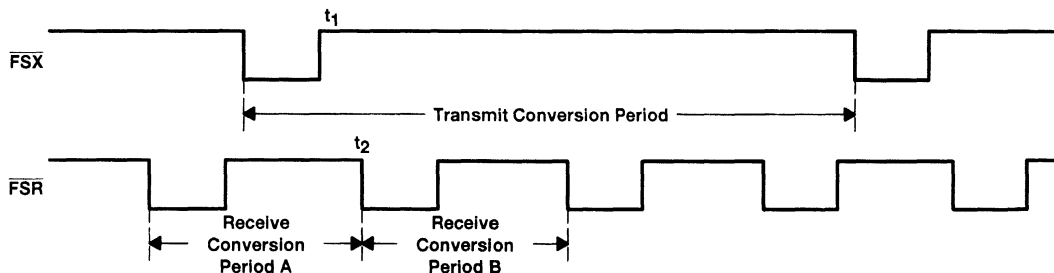
improper operation due to conversion times being too close together

If the difference between two successive D/A conversion frame syncs is less than 1/19.2 kHz, the AIC operates improperly. In this situation, the second D/A conversion frame sync occurs too quickly and there is not enough time for the ongoing conversion to be completed. This situation can occur if the A and B registers are improperly programmed or if the A + A' register or A - A' register result is too small. When incrementally adjusting the conversion period via the A + A' register options, the designer should be very careful not to violate this requirement (see following diagram).



asynchronous operation — more than one receive frame sync occurring between two transmit frame syncs

When incrementally adjusting the conversion period via the A + A' or A - A' register options, a specific protocol is followed. The command to use the incremental conversion period adjust option is sent to the AIC during a $\overline{\text{FSX}}$ frame sync. The ongoing conversion period is then adjusted. However, either receive conversion period A or B may be adjusted. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. Therefore, if there is sufficient time between t_1 and t_2 , the receive conversion period adjustment is performed during receive conversion period A. Otherwise, the adjustment is performed during receive conversion period B. The adjustment command only adjusts one transmit conversion period and one receive conversion period. To adjust another pair of transmit and receive conversion periods, another command must be issued during a subsequent $\overline{\text{FSX}}$ frame (see figure below).

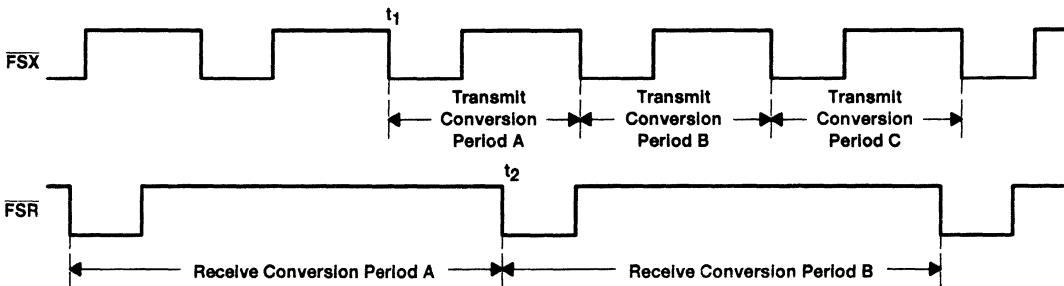


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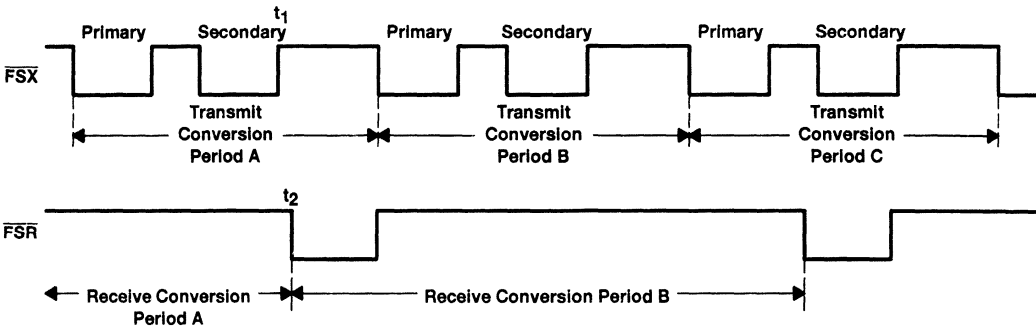
asynchronous operation — more than one receive frame sync occurring between two receive frame syncs

When incrementally adjusting the conversion period via the A + A' or A - A' register options, a specific protocol is followed. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. The command to use the incremental conversion period adjust options is sent to the AIC during a FSX frame sync. The ongoing transmit conversion period is then adjusted. However, three possibilities exist for the receive conversion period adjustment in the diagram as shown in the following figure. If the adjustment command is issued during transmit conversion period A, receive conversion period A is adjusted if there is sufficient time between t_1 and t_2 . Or, if there is not sufficient time between t_1 and t_2 , receive conversion period B is adjusted. Or, the receive portion of an adjustment command can be ignored if the adjustment command is sent during a receive conversion period, which is already being or is adjusted due to a prior adjustment command. For example, if adjustment commands are issued during transmit conversion periods A, B, and C, the first two commands can cause receive conversion periods A and B to be adjusted, while the third receive adjustment command is ignored. The third adjustment command is ignored since it was issued during receive conversion period B, which already is adjusted via the transmit conversion period B adjustment command.



asynchronous operation — more than one set of primary and secondary DX serial communication occurring between two receive frame sync (see AIC DX data word format section)

The TA, TA', TB, and control register information that is transmitted in the secondary communications is always accepted and is applied during the ongoing transmit conversion period. If there is sufficient time between t_1 and t_2 , the TA, RA', and RB register information, which is sent during transmit conversion period A, is applied to receive conversion period A. Otherwise, this information is applied during receive conversion period B. If RA, RA', and RB register information has already been received and is being applied during an ongoing conversion period, any subsequent RA, RA', or RB information that is received during this receive conversion period is disregarded (see diagram below).



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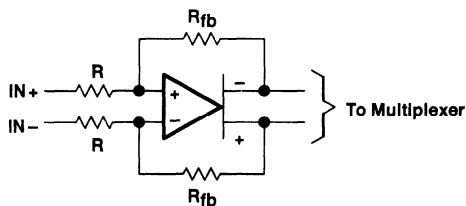
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Table 2. Gain Control Table Analog Input Signal Required for Full-Scale A/D Conversion

INPUT CONFIGURATIONS	CONTROL REGISTER BITS		ANALOG INPUT†	A/D CONVERSION RESULT
	d6	d7		
Differential configuration Analog input = $IN+ - IN-$ = $AUX IN+ - AUX IN-$	1	1	$\pm 6 V$	Full scale
	0	0		
	1	0	$\pm 3 V$	Full scale
	0	1	$\pm 1.5 V$	Full scale
Single-ended configuration Analog input = $IN+ - ANLG GND$ = $AUX IN+ - ANLG GND$	1	1	$\pm 3 V$	Half scale
	0	0		
	1	0	$\pm 3 V$	Full scale
	0	1	$\pm 1.5 V$	Full scale

† In this example, V_{ref} is assumed to be 3 V. In order to minimize distortion, it is recommended that the analog input not exceed 0.1 dB below full scale.



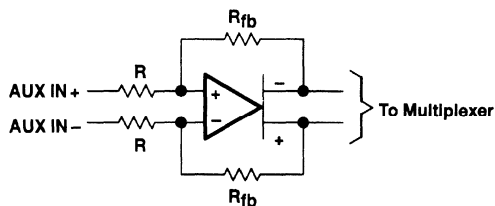
$$R_{fb} = R \text{ for } d6 = 1, d7 = 1$$

$$d6 = 0, d7 = 0$$

$$R_{fb} = 2R \text{ for } d6 = 1, d7 = 0$$

$$R_{fb} = 4R \text{ for } d6 = 0, d7 = 1$$

Figure 2. $IN+$ and $IN-$ Gain Control Circuitry



$$R_{fb} = R \text{ for } d6 = 1, d7 = 1$$

$$d6 = 0, d7 = 0$$

$$R_{fb} = 2R \text{ for } d6 = 1, d7 = 0$$

$$R_{fb} = 4R \text{ for } d6 = 0, d7 = 1$$

Figure 3. $AUX IN+$ and $AUX IN-$ Gain Control Circuitry

(sin x)/x correction section

The AIC does not have $(\sin x)/x$ correction circuitry after the digital-to-analog converter. The $(\sin x)/x$ correction can be accomplished easily and efficiently in digital signal processor (DSP) software. Excellent correction accuracy can be achieved to a band edge of 3000 Hz by using a first-order digital correction filter. The results, which are shown below, are typical of the numerical correction accuracy that can be achieved for sample rates of interest. The filter requires only seven instruction cycles per sample on the TMS320 DSPs. With a 200-ns instruction cycle, nine instructions per sample represents an overhead factor of 1.4% and 1.7% for sampling rates of 8000 Hz and 9600 Hz, respectively. This correction adds a slight amount of group delay at the upper edge of the 300–3000-Hz band.

(sin x)/x roll-off for a zero-order hold function

The (sin x)/x roll-off for the AIC DAC zero-order hold function at a band-edge frequency of 3000 Hz for the various sampling rates is shown in the table below.

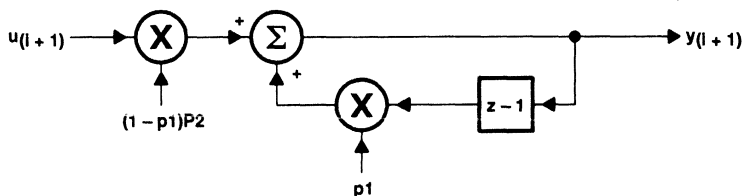
Table 3. (sin x)/x Roll-Off

f_s (Hz)	$20 \log \frac{\sin \pi f/f_s}{\pi f/f_s}$ ($f = 3000$ Hz) (dB)
7200	-2.64
8000	-2.11
9600	-1.44
14400	-0.63
19200	-0.35

The actual AIC (sin x)/x roll-off is slightly less than the above figures, because the AIC has less than a 100% duty cycle hold interval.

correction filter

To compensate for the (sin x)/x roll-off of the AIC, a first-order correction filter shown below, is recommended.



The difference equation for this correction filter is:

$$y_i + 1 = p_2(1 - p_1) (u_{i+1}) + p_1 y_i$$

where the constant p_1 determines the pole locations.

The resulting squared magnitude transfer function is:

$$|H(f)|^2 = \frac{p_2^2 (1 - p_1)^2}{1 - 2p_1 \cos(2 \pi f/f_s) + p_1^2}$$

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correction results

Table 4 below shows the optimum p values and the corresponding correction results for 8000-Hz and 9600-Hz sampling rates.

Table 4. Correction Results

f (Hz)	ERROR (dB)	ERROR (dB)
	$f_s = 8000 \text{ Hz}$ $p1 = -0.14813$ $p2 = 0.9888$	$f_s = 9600 \text{ Hz}$ $p1 = -0.1307$ $p2 = 0.9951$
300	-0.099	-0.043
600	-0.089	-0.043
900	-0.054	0
1200	-0.002	0
1500	0.041	0
1800	0.079	0.043
2100	0.100	0.043
2400	0.091	0.043
2700	-0.043	0
3000	-0.102	-0.043

TMS320 software requirements

The digital correction filter equation can be written in state variable form as follows:

$$Y = k1 \times Y + k2 \times U$$

Where

$$k1 = p1$$

$$k2 = (1 - p1) \times p2$$

Y = filter state

U = next I/O sample

The coefficients k1 and k2 must be represented as 16-bit integers. The SACH instruction (with the proper shift) will yield the correct result. With the assumption that the TMS320 processor page pointer and memory configuration are properly initialized, the equation can be executed in seven instructions or seven cycles with the following program:

```
ZAC
LT K2
MPY U
LTA K1
MPY Y
APAC
SACH (dma), (shift)
```

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absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage range, V_{CC+} (see Note 1)	-0.3 V to 15 V
Supply voltage range, V_{DD}	-0.3 V to 15 V
Output voltage range, V_O	-0.3 V to 15 V
Input voltage range, V_I	-0.3 V to 15 V
Digital ground voltage range	-0.3 V to 15 V
Operating free-air temperature range, T_A : TLC32040C, TLC32041C	0°C to 70°C
TLC32040I, TLC32041I	-40°C to 85°C
Storage temperature range, T_{stg}	-40°C to 125°C
Case temperature for 10 seconds: FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Voltage values for maximum ratings are with respect to V_{CC-} .

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+} (see Note 2)	4.75	5	5.25	V
Supply voltage, V_{CC-} (see Note 2)	-4.75	-5	-5.25	V
Digital supply voltage, V_{DD} (see Note 2)	4.75	5	5.25	V
Digital ground voltage with respect to ANALG GND, DGTL GND	0			V
Reference input voltage, $V_{ref(ext)}$ (see Note 2)	2	4		V
High-level input voltage, V_{IH}	2	$V_{DD}+0.3$		V
Low-level input voltage, V_{IL} (see Note 3)	-0.3	0.8		V
Load resistance at OUT+ and/or OUT-, R_L	300			Ω
Load capacitance at OUT+ and/or OUT-, C_L	100			pF
MSTR CLK frequency (see Note 4)	0.075	5	10.368	MHz
Analog input amplifier common mode input voltage (see Note 5)	± 1.5			V
A/D or D/A conversion rate	20			kHz
Operating free-air temperature, T_A	TLC32040C, TLC32041C			°C
	TLC32040I, TLC32041I			

NOTES: 2. Voltages at analog inputs and outputs, REF, V_{CC+} , and V_{CC-} , are with respect to ANALG GND. Voltages at digital inputs and outputs and V_{DD} are with respect to DGTL GND.

- The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels and temperature only.
- The bandpass low-pass switched-capacitor filter response specifications apply only when the switched-capacitor clock frequency is 288 kHz. For switched-capacitor filter clocks at frequencies other than 288 kHz, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 288 kHz.
- This range applies when (IN+ - IN-) or (AUX IN+ - AUX IN-) equals ± 6 V.



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electrical characteristics over recommended operating free-air temperature range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

total device, MSTR CLK frequency = 5.184 MHz, outputs not loaded

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$V_{DD} = 4.75\text{ V}$, $I_{OH} = -300\ \mu\text{A}$	2.4			V
V_{OL}	Low-level output voltage	$V_{DD} = 4.75\text{ V}$, $I_{OL} = 2\text{ mA}$			0.4	V
I_{CC+}	Supply current from V_{CC+}	TLC3204_C			35	mA
		TLC3204_I			40	
I_{CC-}	Supply current from V_{CC-}	TLC3204_C			-35	mA
		TLC3204_I			-40	
I_{DD}	Supply current from V_{DD}	MSTR CLK = 5.184 MHz			7	mA
V_{ref}	Internal reference output voltage		3		3.3	V
αV_{ref}	Temperature coefficient of internal reference voltage			200		ppm/°C
r_o	Output resistance at REF			100		k Ω

receive amplifier input

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
	A/D converter offset error (filters bypassed)			25	65	mV
	A/D converter offset error (filters in)			25	65	mV
CMRR	Common-mode rejection ratio at IN+, IN-, or AUX IN+, AUX IN-	See Note 6		55		dB
r_i	Input resistance at IN+, IN-, or AUX IN+, AUX IN-, REF			100		k Ω

transmit filter output

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OO}	Output offset voltage at OUT+, OUT-, (single-ended relative to ANLG GND)			15	75	mV
V_{OM}	Maximum peak output voltage swing across R_L at OUT+ or OUT-, (single ended)	$R_L \geq 300\ \Omega$, Offset voltage = 0		± 3		V
V_{OM}	Maximum peak output voltage swing between R_L at OUT+ and OUT-, (differential output)	$R_L \geq 600\ \Omega$		± 6		V

system distortion specifications, SCF clock frequency = 288 kHz

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Attenuation of second harmonic of A/D input signal	Single ended	$V_1 = -0.5\text{ dB to } -24\text{ dB}$ referred to V_{ref} . See Note 7		70		dB
	Differential			62		
Attenuation of third and higher harmonics of A/D input signal	Single ended	$V_1 = -0.5\text{ dB to } -24\text{ dB}$ referred to V_{ref} . See Note 7		65		dB
	Differential			57		
Attenuation of second harmonic of D/A input signal	Single ended	$V_1 = -0\text{ dB to } -24\text{ dB}$ referred to V_{ref} . See Note 7		70		dB
	Differential			62		
Attenuation of third and higher harmonics of D/A input signal	Single ended	$V_1 = -0\text{ dB to } -24\text{ dB}$ referred to V_{ref} . See Note 7		65		dB
	Differential			57		

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTES: 6. The test condition is a 0-dBm, 1-kHz input signal with an 8-kHz conversion rate.

7. The test condition V_1 is a 1-kHz input signal with an 8-kHz conversion rate (0 dB relative to V_{ref}). The load impedance for the DAC is 600 Ω .

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A/D channel signal-to-distortion ratio

PARAMETER	TEST CONDITIONS (see Note 7)	$A_V = 1^\dagger$		$A_V = 2^\dagger$		$A_V = 4^\dagger$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
A/D channel signal-to-distortion ratio	$V_I = -6$ dB to -0.1 dB	58		>58§		>58§		dB
	$V_I = -12$ dB to -6 dB	58		58		>58§		
	$V_I = -18$ dB to -12 dB	56		58		58		
	$V_I = -24$ dB to -18 dB	50		56		58		
	$V_I = -30$ dB to -24 dB	44		50		56		
	$V_I = -36$ dB to -30 dB	38		44		50		
	$V_I = -42$ dB to -36 dB	32		38		44		
	$V_I = -48$ dB to -42 dB	26		32		38		
	$V_I = -54$ dB to -48 dB	20		26		32		

D/A channel signal-to-distortion ratio

PARAMETER	TEST CONDITIONS (see Note 7)	MIN	MAX	UNIT
D/A channel signal-to-distortion ratio	$V_I = -6$ dB to 0 dB	58		dB
	$V_I = -12$ dB to -6 dB	58		
	$V_I = -18$ dB to -12 dB	56		
	$V_I = -24$ dB to -18 dB	50		
	$V_I = -30$ dB to -24 dB	44		
	$V_I = -36$ dB to -30 dB	38		
	$V_I = -42$ dB to -36 dB	32		
	$V_I = -48$ dB to -42 dB	26		
	$V_I = -54$ dB to -48 dB	20		

gain and dynamic range

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
Absolute transmit gain tracking error while transmitting into 600Ω	-48 -dB to 0 -dB signal range, See Note 8	± 0.05		± 0.15	dB
Absolute receive gain tracking error	-48 -dB to 0 -dB signal range, See Note 8	± 0.05		± 0.15	dB
Absolute gain of the A/D channel	Signal input is a -0.5 -dB, 1-kHz sinewave		0.2		dB
Absolute gain of the D/A channel	Signal input is a 0 -dB, 1-kHz sinewave		-0.3		dB

power supply rejection and crosstalk attenuation

PARAMETER	TEST CONDITIONS	MIN	TYP [‡]	MAX	UNIT
V_{CC+} or V_{CC-} supply voltage rejection ratio, receive channel	$f = 0$ to 30 kHz		30		dB
	$f = 30$ kHz to 50 kHz		45		
V_{CC+} or V_{CC-} supply voltage rejection ratio, transmit channel (single ended)	$f = 0$ to 30 kHz		30		dB
	$f = 30$ kHz to 50 kHz		45		
Crosswalk attenuation, transmit-to-receive (single ended)			80		dB

[†] A_V is the programmable gain of the input amplifier.

[‡] All typical values are at $T_A = 25^\circ\text{C}$.

§ A value >58 is overrange and signal clipping occurs.

NOTES: 7. The test condition V_{IN} is a 1-kHz input signal with an 8-kHz conversion rate (0 dB relative to V_{REF}). The load impedance for the DAC is 600Ω .

8. Gain tracking is relative to the absolute gain at 1 kHz and 0 dB (0 dB relative to V_{REF}).



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delay distortion, SCF clock frequency = 288 kHz \pm 2%, input (IN+ – IN–) is \pm 3-V sinewave

Refer to filter response graphs for delay distortion specifications.

TLC32040 and TLC32041 bandpass filter transfer function (see curves), SCF clock frequency = 288 kHz, \pm 2%, input (IN+ – IN–) is a \pm 3-V sinewave (see Note 9)

PARAMETER	TEST CONDITIONS	FREQUENCY RANGE	MIN	MAX	UNIT
Filter gain, (see Note 10)	Input signal reference is 0 dB	f = 100 Hz		-42	dB
		f = 170 Hz		-25	
		300 Hz \leq f \leq 3.4 kHz	-0.5	0.5	
		f = 4 kHz		-16	
		f \geq 4.6 kHz		-58	

low-pass filter transfer function, SCF clock frequency = 288 kHz \pm 2% (see Note 9)

PARAMETER	TEST CONDITIONS	FREQUENCY RANGE	MIN	MAX	UNIT
Filter gain, (see Note 10)	Output signal reference is 0 dB	f \leq 3.4 kHz	-0.5	0.5	dB
		f = 3.6 kHz		-4	
		f = 4 kHz		-30	
		f \geq 4.4 kHz		-58	

serial port

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = -300 μ A	2.4			V
V _{OL} Low-level output voltage	I _{OL} = 2 mA			0.4	V
I _I Input current				\pm 10	μ A
C _i Input capacitance			15		pF
C _o Output capacitance			15		pF

operating characteristics over recommended operating free-air temperature range, V_{CC+} = 5 V, V_{CC-} = -5 V, V_{DD} = 5 V

noise (measurement includes low-pass and bandpass switched-capacitor filters)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Transmit noise	DX input = 00000000000000, constant input code	Single ended	200		μ V rms
			Differential	300	500
		Differential	20		dBmco
Receive noise (see Note 11)	Inputs grounded, gain = 1	300		475	μ V rms
		20		dBmco	

† All typical values are at T_A = 25°C.

NOTES: 9. The above filter specifications are for a switched-capacitor filter clock range of 288 kHz \pm 2%. For switched-capacitor filter clocks at frequencies other than 288 kHz \pm 2%, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 288 kHz.

10. The filter gain outside of the passband is measured with respect to the gain at 1 kHz. The filter gain within the passband is measured with respect to the average gain within the passband. The passbands are 300 to 3400 Hz and 0 to 3400 Hz for the bandpass and low-pass filters respectively.

11. The noise is referred to the input with a buffer gain of one. If the buffer gain is two or four, the noise figure is correspondingly reduced. The noise is computed by statistically evaluating the digital output of the A/D converter.



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timing requirements

serial port recommended input signals

	MIN	MAX	UNIT
$t_c(\text{MCLK})$ Master clock cycle time	95		ns
$t_r(\text{MCLK})$ Master clock rise time		10	ns
$t_f(\text{MCLK})$ Master clock fall time		10	ns
Master clock duty cycle	42%	58%	
RESET pulse duration (see Note 12)	800		ns
$t_{su}(\text{DX})$ DX setup time before SCLK↓	20		ns
$t_h(\text{DX})$ DX hold time after SCLK↓		$t_c(\text{SCLK})/4$	ns

serial port – AIC output signals, $C_L = 30$ pF for SHIFT CLK output, $C_L = 15$ pF for all other outputs

	MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$ Shift clock (SCLK) cycle time	380			ns
$t_f(\text{SCLK})$ Shift clock (SCLK) fall time		3	8	ns
$t_r(\text{SCLK})$ Shift clock (SCLK) rise time		3	8	ns
Shift clock (SCLK) duty cycle	45		55	%
$t_d(\text{CH-FL})$ Delay from SCLK↑ to FSR/FSX/FSD↓		30		ns
$t_d(\text{CH-FH})$ Delay from SCLK↑ to FSR/FSX/FSD↑		35	90	ns
$t_d(\text{CH-DR})$ DR valid after SCLK↑			90	ns
$t_d(\text{CH-EL})$ Delay from SCLK↑ to EODX/EODR↓ in word mode			90	ns
$t_d(\text{CH-EH})$ Delay from SCLK↑ to EODX/EODR↑ in word mode			90	ns
$t_f(\text{EODX})$ EODX fall time		2	8	ns
$t_f(\text{EODR})$ EODR fall time		2	8	ns
$t_d(\text{CH-EL})$ Delay from SCLK↑ to EODX/EODR↓ in byte mode			90	ns
$t_d(\text{CH-EH})$ Delay from SCLK↑ to EODX/EODR↑ in byte mode			90	ns
$t_d(\text{MH-SL})$ Delay from MSTR CLK↑ to SCLK↓		65	170	ns
$t_d(\text{MH-SH})$ Delay from MSTR CLK↑ to SCLK↑		65	170	ns

† Typical values are at $T_A = 25^\circ\text{C}$.

NOTE 12: RESET pulse duration is the amount of time that the reset terminal is held below 0.8 V after the power supplies have reached their recommended values.

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serial port – AIC output signals

		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$	Shift clock (SCLK) cycle time		380			ns
$t_f(\text{SCLK})$	Shift clock (SCLK) fall time				50	ns
$t_r(\text{SCLK})$	Shift clock (SCLK) rise time				50	ns
	Shift clock (SCLK) duty cycle		45		55	%
$t_d(\text{CH-FL})$	Delay from SCLK↑ to $\overline{\text{FSR}}/\overline{\text{FSX}}\downarrow$	$C_L = 50 \text{ pF}$			52	ns
$t_d(\text{CH-FH})$	Delay from SCLK↑ to $\overline{\text{FSR}}/\overline{\text{FSX}}\uparrow$	$C_L = 50 \text{ pF}$			52	ns
$t_d(\text{CH-DR})$	DR valid after SCLK↑				90	ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\downarrow$ in word mode				90	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\uparrow$ in word mode				90	ns
$t_f(\text{EODX})$	$\overline{\text{EODX}}$ fall time				15	ns
$t_f(\text{EODR})$	$\overline{\text{EODR}}$ fall time				15	ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\downarrow$ in byte mode				100	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\uparrow$ in byte mode				100	ns
$t_d(\text{MH-SL})$	Delay from MSTR CLK↑ to SCLK↓			65		ns
$t_d(\text{MH-SH})$	Delay from MSTR CLK↑ to SCLK↑			65		ns

† Typical values are at $T_A = 25^\circ\text{C}$.



PARAMETER MEASUREMENT INFORMATION

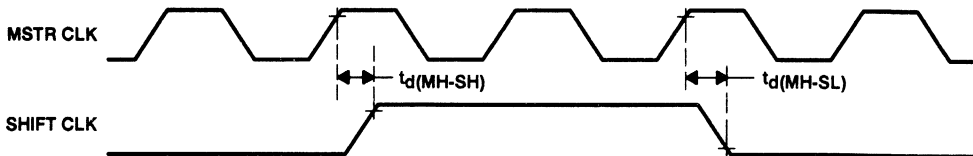
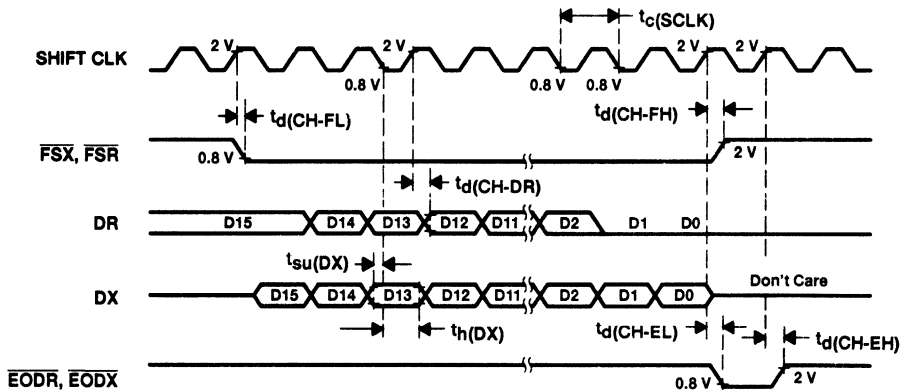
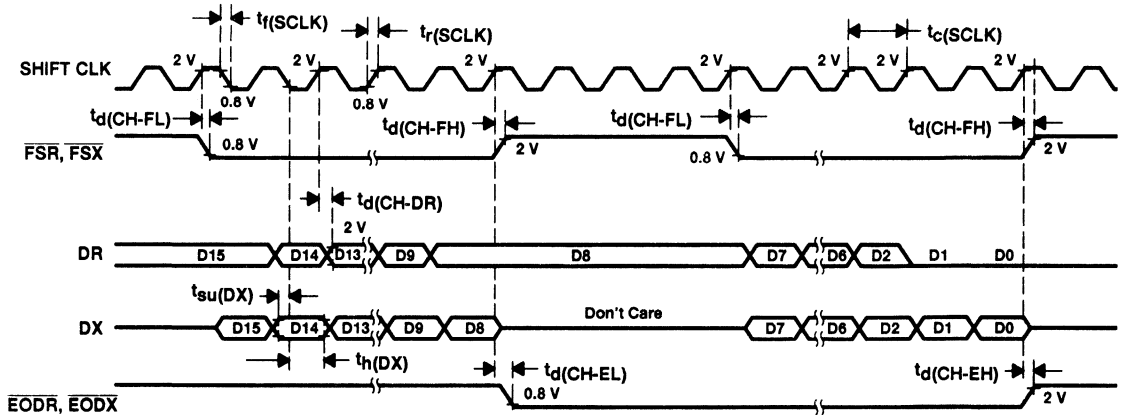


Figure 4. Serial Port Timing

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PARAMETER MEASUREMENT INFORMATION

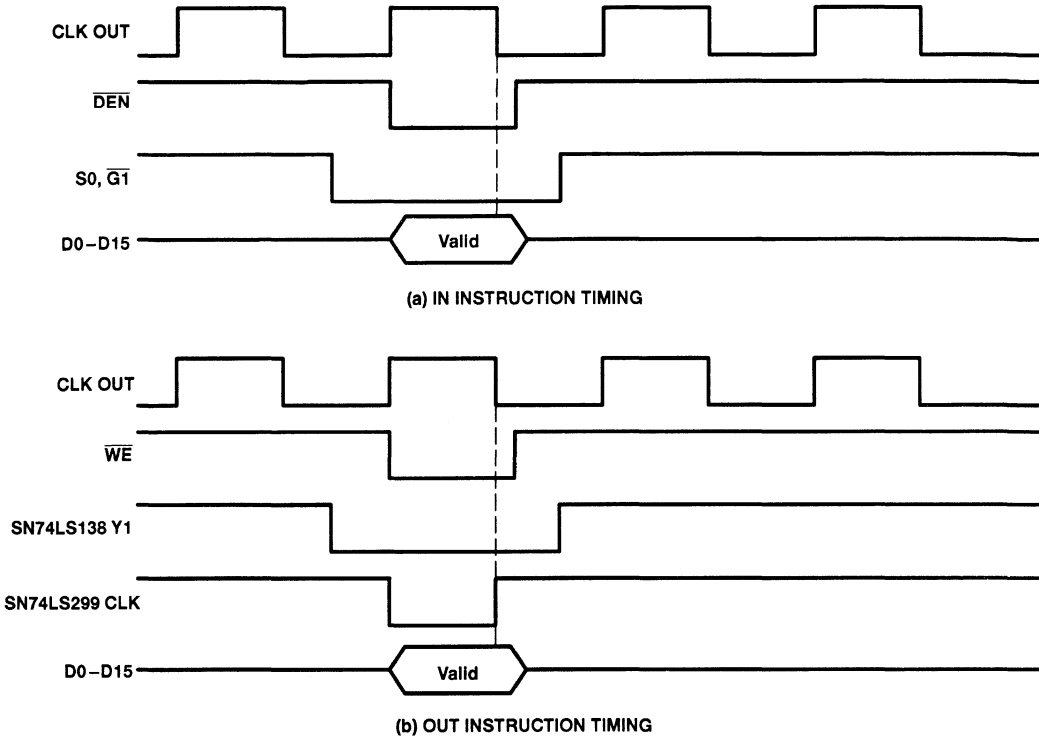
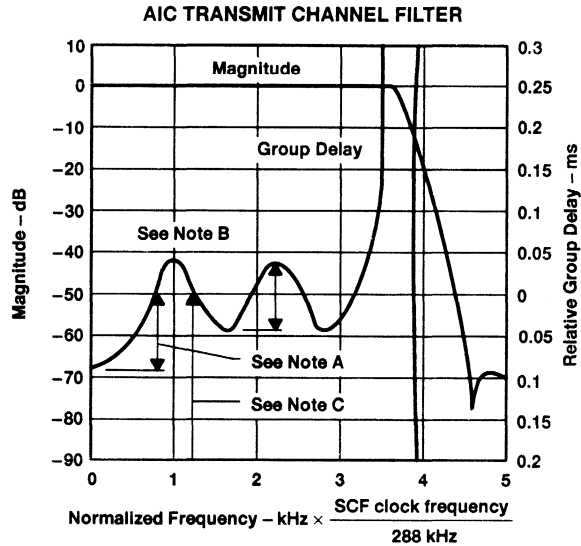


Figure 5. TMS32010-TLC32040/TLC32041 Interface Timing

TYPICAL CHARACTERISTICS



- NOTES: A. Maximum relative delay (0 Hz to 600 Hz) = 125 μ s
 B. Maximum relative delay (600 Hz to 3000 Hz) = \pm 50 μ s
 C. Absolute delay (600 Hz to 3000 Hz) = 700 μ s
 D. Test conditions are V_{CC+} , V_{CC-} , and V_{DD} within recommended operating conditions, SCF clock $f = 288 \text{ kHz} \pm 2\%$ input = $\pm 3\text{-V}$ sinewave, and $T_A = 25^\circ\text{C}$.

Figure 6

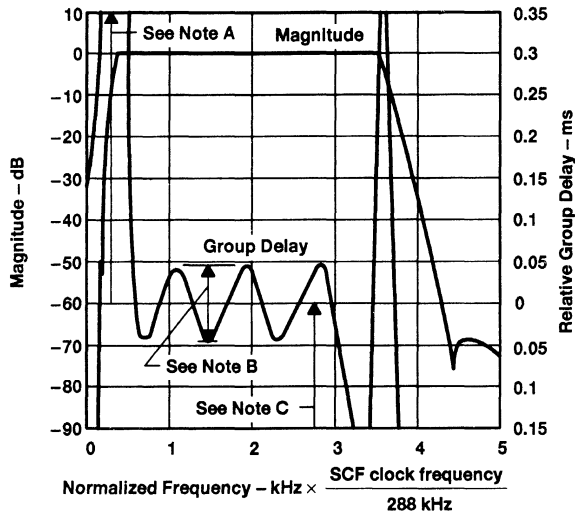
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TYPICAL CHARACTERISTICS

TLC32040 AND TLC32041
RECEIVE CHANNEL FILTER



- NOTES: A. Maximum relative delay (200 Hz to 600 Hz) = 3350 μ s
 B. Maximum relative delay (600 Hz to 3000 Hz) = \pm 50 μ s
 C. Absolute delay (600 Hz to 3000 Hz) = 1230 μ s
 D. Test conditions are V_{CC+} , V_{CC-} , and V_{DD} within recommended operating conditions, SCF clock f = 288 kHz \pm 2%, input = \pm 3-V sinewave, and T_A = 25°C.

Figure 7

TYPICAL CHARACTERISTICS

A/D SIGNAL-TO-DISTORTION RATIO
vs
INPUT SIGNAL

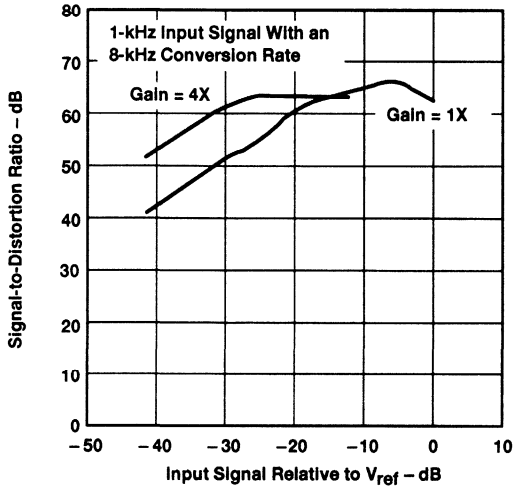


Figure 8

A/D GAIN TRACKING
(GAIN RELATIVE TO GAIN
AT 0-dB INPUT SIGNAL)

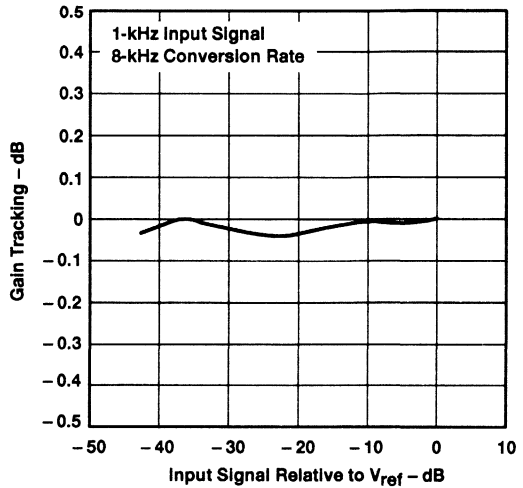


Figure 9

D/A CONVERTER SIGNAL-TO-DISTORTION RATIO
vs
INPUT SIGNAL

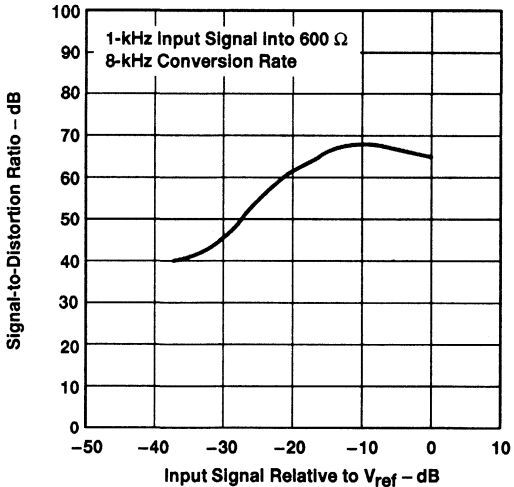


Figure 10

D/A GAIN TRACKING
vs
(GAIN RELATIVE TO GAIN
AT 0 dB INPUT SIGNAL)

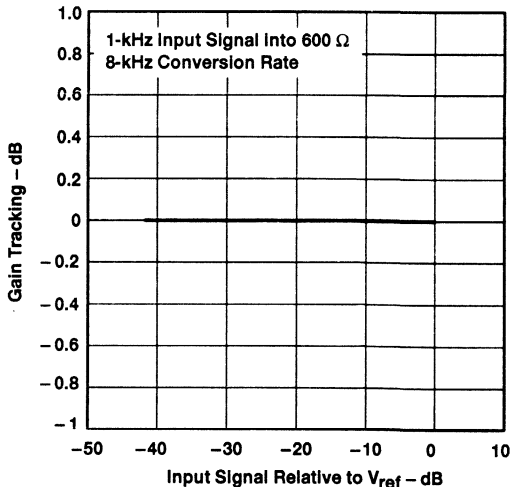


Figure 11

NOTE: Test conditions are V_{CC+} , V_{CC-} , V_{DD} and within recommended operating conditions set clock $f = 288 \text{ kHz} \pm 2\%$, and $T_A = 25^\circ\text{C}$.

TLC32040C, TLC32040I, TLC32041C, TLC32041I ANALOG INTERFACE CIRCUITS

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TYPICAL CHARACTERISTICS

ATTENUATION OF SECOND HARMONIC OF A/D INPUT
vs
INPUT SIGNAL

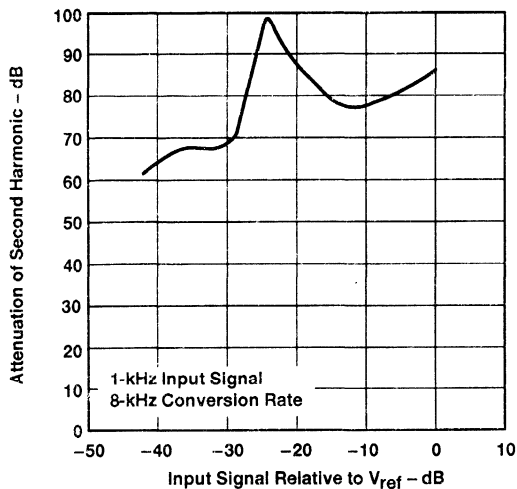


Figure 12

ATTENUATION OF THIRD HARMONIC OF A/D INPUT
vs
INPUT SIGNAL

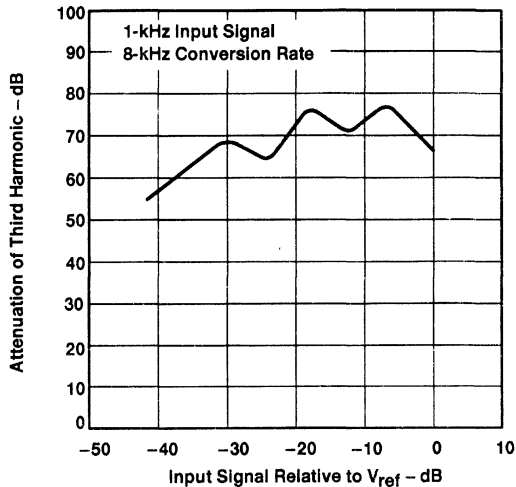


Figure 13

ATTENUATION OF SECOND HARMONIC OF D/A INPUT
vs
INPUT SIGNAL

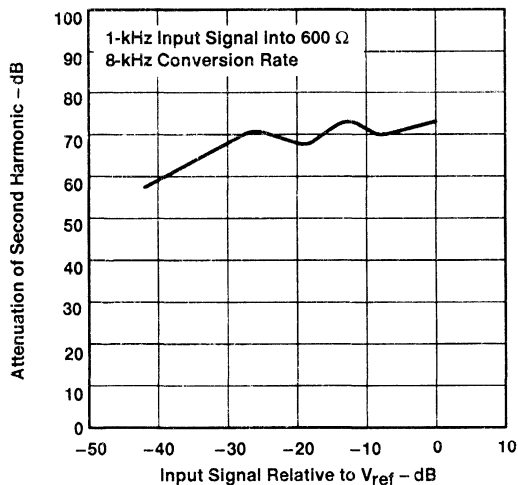


Figure 14

ATTENUATION OF THIRD HARMONIC OF D/A INPUT
vs
INPUT SIGNAL

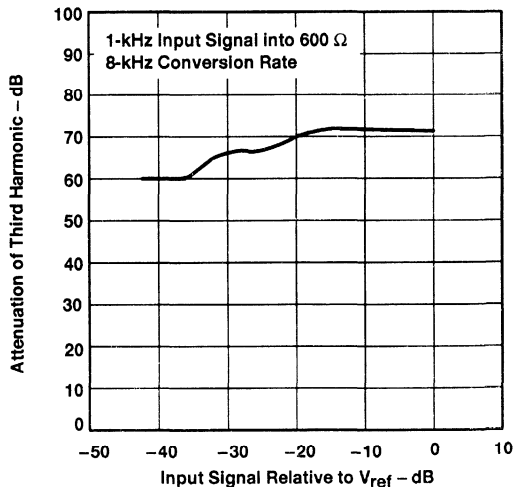


Figure 15

NOTE: Test conditions are V_{CC+} , V_{CC-} , and V_{DD} within recommended operating conditions set clock $f = 288 \text{ kHz} \pm 2\%$, and $T_A = 25^\circ\text{C}$.

TLC32040C, TLC32040I, TLC32041C, TLC32041I ANALOG INTERFACE CIRCUITS

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APPLICATION INFORMATION

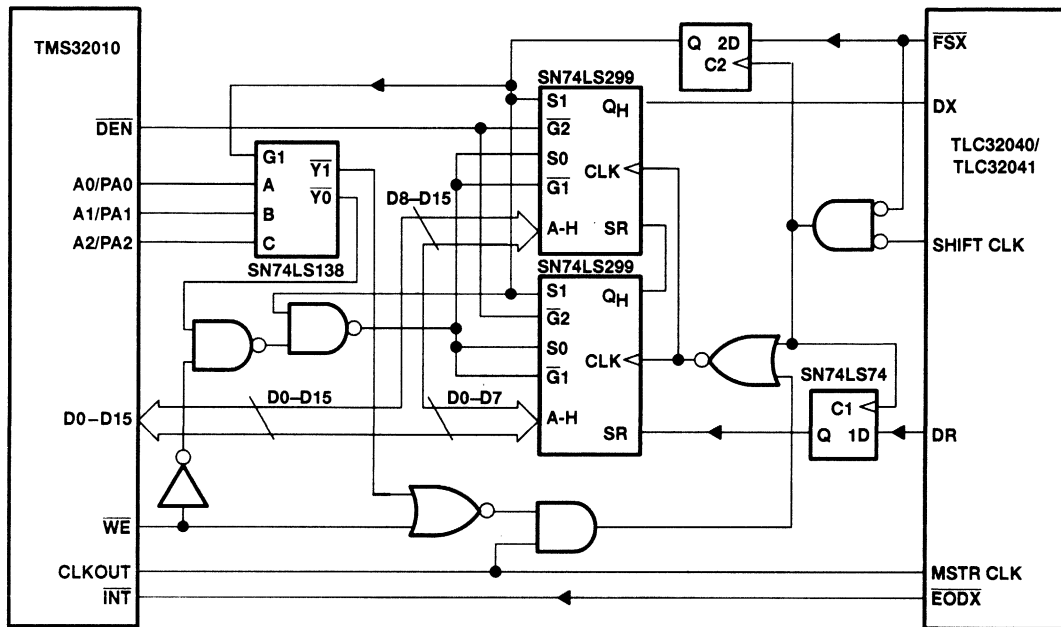


Figure 16. TMS32010-TLC32040/TLC32041 Interface Circuit

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APPLICATION INFORMATION

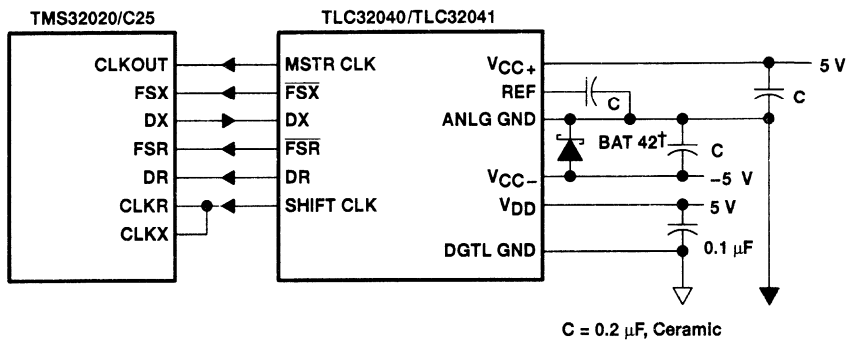


Figure 17. AIC Interface to the TMS32020/C25 Showing Decoupling Capacitors and Schottky Diode†

† Thomson Semiconductors

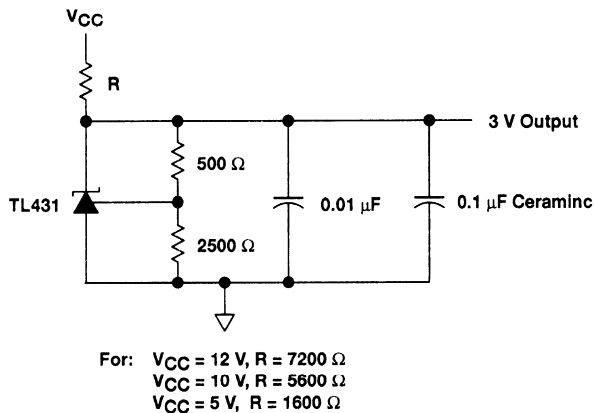


Figure 18. External Reference Circuit For TLC32045

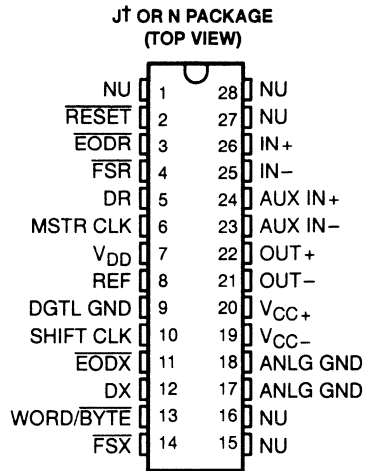
TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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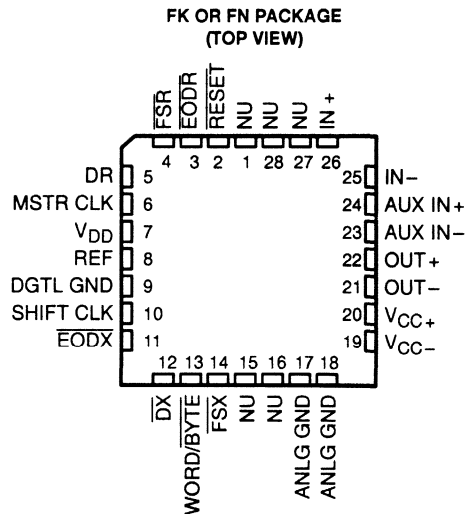
- 14-Bit Dynamic Range ADC and DAC
- 2's Complement Format
- Variable ADC and DAC Sampling Rate Up to 19,200 Samples per Second
- Switched-Capacitor Antialiasing Input Filter and Output-Reconstruction Filter
- Serial Port for Direct Interface to TMS(SMJ)320C17, TMS(SMJ)32020, TMS(SMJ)320C25, and TMS320C30 Digital Signal Processors
- Synchronous or Asynchronous ADC and DAC Conversion Rates With Programmable Incremental ADC and DAC Conversion Timing Adjustments
- Serial Port Interface to SN74(54)299 Serial-to-Parallel Shift Register for Parallel Interface to TMS(SMJ)32010, TMS(SMJ)320C15, or Other Digital Processors
- Internal Reference for Normal Operation and External Purposes, or Can Be Overridden by External Reference
- CMOS Technology

description

The TLC32044 and TLC32045 are complete analog-to-digital and digital-to-analog input and output systems on single monolithic CMOS chips. The TLC32044 and TLC32045 integrate a bandpass switched-capacitor antialiasing input filter, a 14-bit-resolution A/D converter, four microprocessor-compatible serial port modes, a 14-bit-resolution D/A converter, and a low-pass switched-capacitor output-reconstruction filter. The devices offer numerous combinations of master clock input frequencies and conversion/sampling rates, which can be changed via digital processor control.



† Refer to the mechanical data for the JT package.



NU – Nonusable; no external connection should be made to these terminals (see Table 2).

AVAILABLE OPTIONS

T _A	PACKAGE			
	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)	CERAMIC DIP (J)	CHIP CARRIER (FK)
0°C to 70°C	TLC32044CFN	TLC32044CN		
	TLC32045CFN	TLC32045CN		
-20°C to 85°C	TLC32044EFN			
-40°C to 85°C		TLC32044IN		
		TLC32045IN		
-55°C to 125°C			TLC32044MJ	TLC32044MFK

PRODUCTION DATA Information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



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TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I

VOICE-BAND ANALOG INTERFACE CIRCUITS

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description (continued)

Typical applications for the TLC32044 and TLC32045 include speech encryption for digital transmission, speech recognition/storage systems, speech synthesis, modems (7.2-, 8-, 9.6-, 14.4-, and 19.2-kHz sampling rate), analog interface for digital signal processors (DSPs), industrial process control, biomedical instrumentation, acoustical signal processing, spectral analysis, data acquisition, and instrumentation recorders. Four serial modes, which allow direct interface to the TMS(SMJ)320C17, TMS(SMJ)32020, TMS(SMJ)320C25, and TMS(SMJ)320C30 digital signal processors, are provided. Also, when the transmit and receive sections of the analog interface circuit (AIC) are operating synchronously, it will interface to two SN74(54)299 serial-to-parallel shift registers. These serial-to-parallel shift registers can then interface in parallel to the TMS(SMJ)32010, TMS(SMJ)320C15, and other digital signal processors, or external FIFO circuitry. Output data pulses are emitted to inform the processor that data transmission is complete or to allow the DSP to differentiate between two transmitted bytes. A flexible control scheme is provided so that the functions of the TLC32044 or TLC32045 can be selected and adjusted coincidentally with signal processing via software control.

The antialiasing input filter comprises eighth-order and fourth-order CC-type (Chebyshev/elliptic transitional) low-pass and high-pass filters, respectively. The input filter is implemented in switched-capacitor technology and is preceded by a continuous time filter to eliminate any possibility of aliasing caused by sampled data filtering. When only low-pass filtering is desired, the high-pass filter can be switched out of the signal path. A selectable, auxiliary, differential analog input is provided for applications where more than one analog input is required.

The A/D and D/A architectures ensure no missing codes and monotonic operation. An internal voltage reference is provided to ease the design task and to provide complete control over the performance of the TLC32044 or TLC32045. The internal voltage reference is brought out to a terminal and is available to the designer. Separate analog and digital voltage supplies and grounds are provided to minimize noise and ensure a wide dynamic range. Also, the analog circuit path contains only differential circuitry to keep noise to an absolute minimum. The only exception is the DAC sample and hold, which utilizes pseudo-differential circuitry.

The output-reconstruction filter is an eighth-order CC-type (Chebyshev/elliptic transitional low-pass filter) followed by a second-order $(\sin x)/x$ correction filter and is implemented in switched-capacitor technology. This filter is followed by a continuous-time filter to eliminate images of the digitally encoded signal. The on-board $(\sin x)/x$ correction filter can be switched out of the signal path using digital signal processor control, if desired.

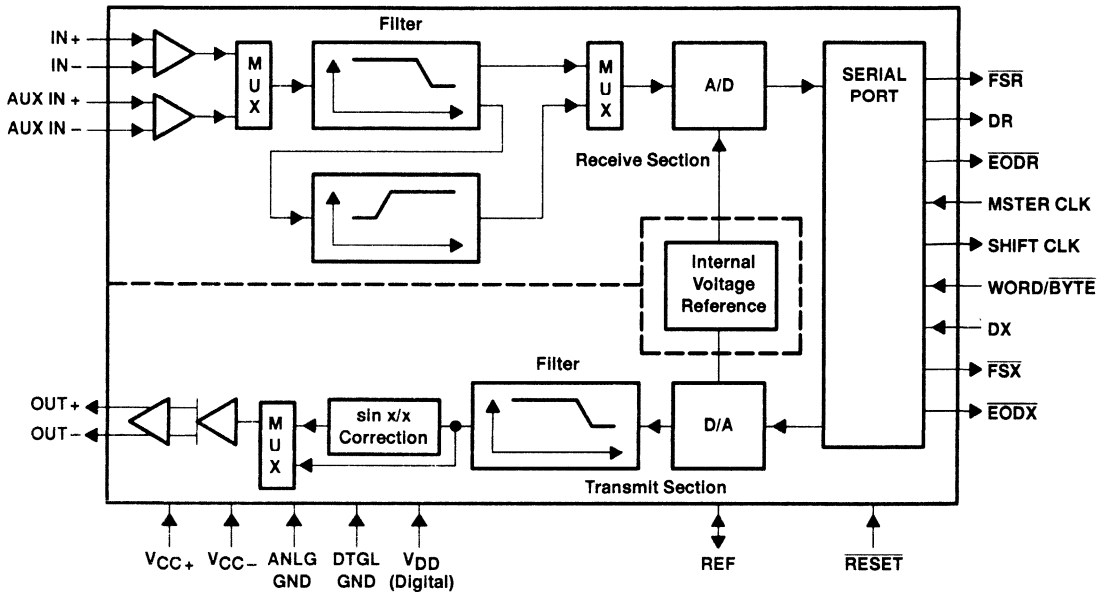
The TLC32044C and TLC32045C are characterized for operation from 0°C to 70°C. The TLC32044E is characterized for operation from -20°C to 85°C. The TLC32044I and TLC32045I are characterized for operation from -40°C to 85°C. The TLC32044M is characterized for operation from -55°C to 125°C.



TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANLG GND	17,18		Analog ground return for all internal analog circuits. Not internally connected to DGTL GND.
AUX IN+	24	I	Noninverting auxiliary analog input stage. AUX IN+ can be switched into the bandpass filter and A/D converter path via software control. If the appropriate bit in the control register is a 1, the auxiliary inputs will replace the IN+ and IN- inputs. If the bit is a 0, the IN+ and IN- inputs will be used (see the AIC DX data word format section).
AUX IN-	23	I	Inverting auxiliary analog input (see the above AUX IN+ description).
DGTL GND	9		Digital ground for all internal logic circuits. Not internally connected to ANLG GND.
DR	5	O	Data receive. DR is used to transmit the ADC output bits from the AIC to the TMS320 (SMJ320) serial port. This transmission of bits from the AIC to the TMS320 (SMJ320) serial port is synchronized with the SHIFT CLK signal.
DX	12	I	Data transmit. DX is used to receive the DAC input bits and timing and control information from the TMS320 (SMJ320). This serial transmission from the TMS320 (SMJ320) serial port to the AIC is synchronized with the SHIFT CLK signal.
EODR	3	O	End of data receive. (See the WORD/BYTE description and Serial Port Timing diagram.) During the word-mode timing, EODR is a low-going pulse that occurs immediately after the 16 bits of A/D information have been transmitted from the AIC to the TMS320 (SMJ320) serial port. EODR can be used to interrupt a microprocessor upon completion of serial communications. Also, EODR can be used to strobe and enable external serial-to-parallel shift registers, latches, or external FIFO RAM, and to facilitate parallel data bus communications between the AIC and the serial-to-parallel shift registers. During the byte-mode timing, EODR goes low after the first byte has been transmitted from the AIC to the TMS320 (SMJ320) serial port and is kept low until the second byte has been transmitted. The DSP can use this low-going signal to differentiate between the two bytes as to which is first and which is second. EODR does not occur after secondary communication.

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
$\overline{\text{EODX}}$	11	O	End of data transmit. (See the WORD/BYTE description and Serial Port Timing diagram.) During the word-mode timing, $\overline{\text{EODX}}$ is a low-going pulse that occurs immediately after the 16 bits of D/A converter and control or register information have been transmitted from the TMS320 (SMJ320) serial port to the AIC. $\overline{\text{EODX}}$ can be used to interrupt a microprocessor upon the completion of serial communications. Also, $\overline{\text{EODX}}$ can be used to strobe and enable external serial-to-parallel shift registers, latches, or an external FIFO RAM, and to facilitate parallel data-bus communications between the AIC and the serial-to-parallel shift registers. During the byte-mode timing, $\overline{\text{EODX}}$ goes low after the first byte has been transmitted from the TMS320 (SMJ320) serial port to the AIC and is kept low until the second byte has been transmitted. The DSP can use this low-going signal to differentiate between the two bytes as to which is first and which is second.
FSR	4	O	Frame sync receive. In the serial transmission modes, which are described in the WORD/BYTE description, FSR is held low during bit transmission. When FSR goes low, the TMS320 (SMJ320) serial port begins receiving bits from the AIC via DR of the AIC. The most significant DR bit is present on DR before FSR goes low. (See Serial Port Timing and Internal Timing Configuration diagrams.) FSR does not occur after secondary communications.
FSX	14	O	Frame sync transmit. When FSX goes low, the TMS320 (SMJ320) serial port begins transmitting bits to the AIC via DX of the AIC. In all serial transmission modes, which are described in the WORD/BYTE description, FSX is held low during bit transmission (see Serial Port Timing and Internal Timing Configuration diagrams).
IN+	26	I	Noninverting input to analog input amplifier stage
IN-	25	I	Inverting input to analog input amplifier stage
MSTR CLK	6	I	Master clock. MSTR CLK is used to derive all the key logic signals of the AIC, such as the shift clock, the switched-capacitor filter clocks, and the A/D and D/A timing signals. The Internal Timing Configuration diagram shows how these key signals are derived. The frequencies of these key signals are synchronous submultiples of the master clock frequency to eliminate unwanted aliasing when the sampled analog signals are transferred between the switched-capacitor filters and the A/D and D/A converters (see the Internal Timing Configuration diagram).
OUT+	22	O	Noninverting output of analog output power amplifier. OUT+ can drive transformer hybrids or high-impedance loads directly in either a differential or a single-ended configuration.
OUT-	21	O	Inverting output of analog output power amplifier. OUT- is functionally identical with and complementary to OUT+.
REF	8	I/O	Internal voltage reference. An internal reference voltage is brought out on REF. An external voltage reference can also be applied to REF.
$\overline{\text{RESET}}$	2	I	Reset function. $\overline{\text{RESET}}$ is provided to initialize the TA, TA', TB, RA, RA', RB, and control registers. A reset initiates serial communications between the AIC and DSP. A reset initializes all AIC registers including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC registers are initialized to provide an 8-khz data conversion rate for a 5.184-MHz master clock input signal. The conversion rate adjust registers, TA' and RA', are reset to 1. The control register bits are reset as follows (see AIC DX data word format section): d9 = 1, d7 = 1, d6 = 1, d5 = 1, d4 = 0, d3 = 0, d2 = 1. This initialization allows normal serial-port communication to occur between the AIC and DSP.
SHIFT CLK	10	O	Shift clock. SHIFT CLK is obtained by dividing the master clock signal frequency by four. SHIFT CLK is used to clock the serial data transfers of the AIC, described in the WORD/BYTE description below (see the Serial Port Timing and Internal Timing Configuration diagrams).
VDD	7		Digital supply voltage, 5 V \pm 5%
VCC+	20		Positive analog supply voltage, 5 V \pm 5%
VCC-	19		Negative analog supply voltage, -5 V \pm 5%



TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
WORD/BYTE	13	I	<p>Used in conjunction with a bit in the control register, WORD/BYTE is used to establish one of four serial modes. These four serial modes are described below. <i>AIC transmit and receive sections are operated asynchronously.</i> The following description applies when the AIC is configured to have asynchronous transmit and receive sections. If the appropriate data bit in the control register is a 0 (see the AIC DX data word format section), the transmit and receive sections are asynchronous.</p> <p style="margin-left: 20px;">L Serial port directly interfaces with the serial port of the DSP and communicates in two 8-bit bytes. The operation sequence is as follows (see Serial Port Timing diagrams).</p> <ol style="list-style-type: none"> FSX or FSR is brought low. One 8-bit byte is transmitted or one 8-bit byte is received. EODX or EODR is brought low. FSX or FSR emits a positive frame-sync pulse that is four shift clock cycles wide. One 8-bit byte is transmitted or one 8-bit byte is received. EODX or EODR is brought high. FSX or FSR is brought high. <p style="margin-left: 20px;">H Serial port directly interfaces with the serial ports of the TMS(SMJ)32020, TMS(SMJ)320C25, or TMS(SMJ)320C30, and communicates in one 16-bit word. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX or FSR is brought low. One 16-bit word is transmitted or one 16-bit word is received. FSX or FSR is brought high. EODX or EODR emits a low-going pulse. <p><i>AIC transmit and receive sections are operated synchronously.</i> If the appropriate data bit in the control register is 1, the transmit and receive sections are configured to be synchronous. In this case, the bandpass switched-capacitor filter and the A/D conversion timing are derived from the TX counter A, TX counter B, and TA, TA', and TB registers, rather than the RX counter A, RX counter B, and RA, RA', and RB registers. In this case, the AIC FSX and FSR timing are identical during primary data communication; however, FSR is not asserted during secondary data communication since there is no new A/D conversion result. The synchronous operation sequences are as follows (see Serial Port Timing diagrams).</p> <p style="margin-left: 20px;">L Serial port directly interfaces with the serial port of the DSP and communicates in two 8-bit bytes. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX and FSR are brought low. One 8-bit byte is transmitted and one 8-bit byte is received. EODX and EODR are brought low. FSX and FSR emit positive frame-sync pulses that are four shift clock cycles wide. One 8-bit byte is transmitted and one 8-bit byte is received. EODX and EODR are brought high. FSX and FSR are brought high. <p style="margin-left: 20px;">H Serial port directly interfaces with the serial port of the TMS(SJM)32020, TMS(SMJ)320C25, or TMS320C30, and communicates in one 16-bit word. The operation sequence is as follows (see Serial Port Timing diagrams):</p> <ol style="list-style-type: none"> FSX and FSR are brought low. One 16-bit word is transmitted and one 16-bit word is received. FSX and FSR are brought high. EODX or EODR emit low-going pulses. <p>Since the transmit and receive sections of the AIC are now synchronous, the AIC serial port with additional NOR and AND gates interface to two SN74(54)299 serial-to-parallel shift registers. Interfacing the AIC to the SN74(54)299 shift register allows the AIC to interface to an external FIFO RAM and facilitates parallel, data bus communications between the AIC and the digital signal processor. The operation sequence is the same as the above sequence (see Serial Port Timing diagrams).</p>

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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PRINCIPLES OF OPERATION

analog input

Two sets of analog inputs are provided. Normally, the IN+ and IN– input set is used; however, the auxiliary input set, AUX IN+ and AUX IN–, can be used if a second input is required. Each input set can be operated in either differential or single-ended modes, since sufficient common-mode range and rejection are provided. The gain for the IN+, IN–, AUX IN+, and AUX IN– inputs can be programmed to be either 1, 2, or 4 (see Table 2). Either input circuit can be selected via software control. It is important to note that a wide dynamic range is assured by the differential internal analog architecture and by the separate analog and digital voltage supplies and grounds.

A/D bandpass filter, A/D bandpass filter clocking, and A/D conversion timing

The A/D high-pass filter can be selected or bypassed via software control. The frequency response of this filter is presented in the following pages. This response results when the switched-capacitor filter clock frequency is 288 kHz and the A/D sample rate is 8 kHz. Several possible options can be used to attain a 288-kHz switched-capacitor filter clock. When the filter clock frequency is not 288 kHz, the low-pass filter transfer function is frequency scaled by the ratio of the actual clock frequency to 288 kHz. The ripple bandwidth and 3-dB low-frequency roll-off points of the high-pass section are 150 Hz and 100 Hz, respectively. However, the high-pass section low-frequency roll-off is frequency scaled by the ratio of the A/D sample rate to 8 kHz.

The internal timing configuration and AIC DX data word format sections of this data sheet indicate the many options for attaining a 288-kHz bandpass switched-capacitor filter clock. These sections indicate that the RX counter A can be programmed to give a 288-kHz bandpass switched-capacitor filter clock for several master clock input frequencies.

The A/D conversion rate is then attained by frequency dividing the 288-kHz bandpass switched-capacitor filter clock with the RX counter B. Unwanted aliasing is prevented because the A/D conversion rate is an integral submultiple of the bandpass switched-capacitor filter sampling rate, and the two rates are synchronously locked.

A/D converter performance specifications

Fundamental performance specifications for the A/D converter circuitry are presented in the A/D converter operating characteristics section of this data sheet. The realization of the A/D converter circuitry with switched-capacitor techniques provides an inherent sample-and-hold.

analog output

The analog output circuitry is an analog output power amplifier. Both noninverting and inverting amplifier outputs are brought out. This amplifier can drive transformer hybrids or low-impedance loads directly in either a differential or single-ended configuration.

D/A low-pass filter, D/A low-pass filter clocking, and D/A conversion timing

The frequency response of this filter is presented in the following pages. This response results when the low-pass switched-capacitor filter clock frequency is 288 kHz. Like the A/D filter, the transfer function of this filter is frequency scaled when the clock frequency is not 288 kHz. A continuous-time filter is provided on the output of the $(\sin x)/x$ correction filter to eliminate the periodic sample data signal information, which occurs at multiples of the 288-kHz switched-capacitor filter clock. The continuous time filter also greatly attenuates any switched-capacitor clock feedthrough.



PRINCIPLES OF OPERATION

D/A low-pass filter, D/A low-pass filter clocking, and D/A conversion timing (continued)

The D/A conversion rate is attained by frequency dividing the 288-kHz switched-capacitor filter clock with TX Counter B. Unwanted aliasing is prevented because the D/A conversion rate is an integral submultiple of the switched-capacitor low-pass filter sampling rate, and the two rates are synchronously locked.

asynchronous versus synchronous operation

If the transmit section of the AIC (low-pass filter and DAC) and receive section (bandpass filter and ADC) are operated asynchronously, the low-pass and bandpass filter clocks are independently generated from the master clock signal. Also, the D/A and A/D conversion rates are independently determined. If the transmit and receive sections are operated synchronously, the low-pass filter clock drives both low-pass and bandpass filters. In synchronous operation, the A/D conversion timing is derived from, and is equal to, the D/A conversion timing (see description of the WORD/BYTE in the Terminal Functions table.)

D/A converter performance specifications

Fundamental performance specifications for the D/A converter circuitry are presented in the D/A converter operating characteristics section of the data sheet. The D/A converter has a sample-and-hold that is realized with a switched-capacitor ladder.

system frequency response correction

The $(\sin x)/x$ correction for the D/A converter zero-order sample-and-hold output can be provided by an on-board second-order $(\sin x)/x$ correction filter. This $(\sin x)/x$ correction filter can be inserted into or deleted from the signal path by digital signal processor control. When inserted, the $(\sin x)/x$ correction filter follows the switched-capacitor low-pass filter. When the TB register (see Internal Timing Configuration section) equals 36, the correction results of Figures 11 and 12 can be obtained.

The $(\sin x)/x$ correction can also be accomplished by deleting the on-board second-order correction filter and performing the $(\sin x)/x$ correction in digital signal processor software. The system frequency response can be corrected via DSP software to ± 0.1 -dB accuracy to a band edge of 3000 Hz for all sampling rates. This correction is accomplished with a first-order digital correction filter, which requires only seven TMS320 (SMJ320) instruction cycles. With a 200-ns instruction cycle, seven instructions represent an overhead factor of only 1.1% and 1.3% for sampling rates of 8 and 9.6 kHz, respectively (see the $(\sin x)/x$ correction section for more details).

serial port

The serial port has four possible modes that are described in detail in the Terminal Functions table. These modes are briefly described below and in the functional description for WORD/BYTE.

- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the DSP.
- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS(SMJ)32020, TMS(SMJ)320C25, and the TMS(SMJ)320C30.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the DSP.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS(SMJ)32020, TMS(SMJ)320C25, TMS(SMJ)320C30, or two SN74(54)299 serial-to-parallel shift registers, which can then interface in parallel to the TMS(SMJ)32010, TMS(SMJ)320C15, and SMJ320E15 to any other digital signal processor or to external FIFO circuitry.

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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PRINCIPLES OF OPERATION

operation of TLC32044 or TLC32045 with internal voltage reference

The internal reference eliminates the need for an external voltage reference and provides overall circuit cost reduction. Thus, the internal reference eases the design task and provides complete control over device performance. The internal reference is brought out to a terminal and is available to the designer. To keep the amount of noise on the reference signal to a minimum, an external capacitor can be connected between REF and ANLG GND.

operation of TLC32044 or TLC32045 with external voltage reference

REF can be driven from an external reference circuit. This external circuit must be capable of supplying 250 μ A and must be adequately protected from noise such as crosstalk from the analog input.

reset

A reset function is provided to initiate serial communications between the AIC and DSP and to allow fast, cost-effective testing during manufacturing. The reset function initializes all AIC registers, including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC is initialized. This initialization allows normal serial port communications activity to occur between AIC and DSP (see AIC DX data word format section).

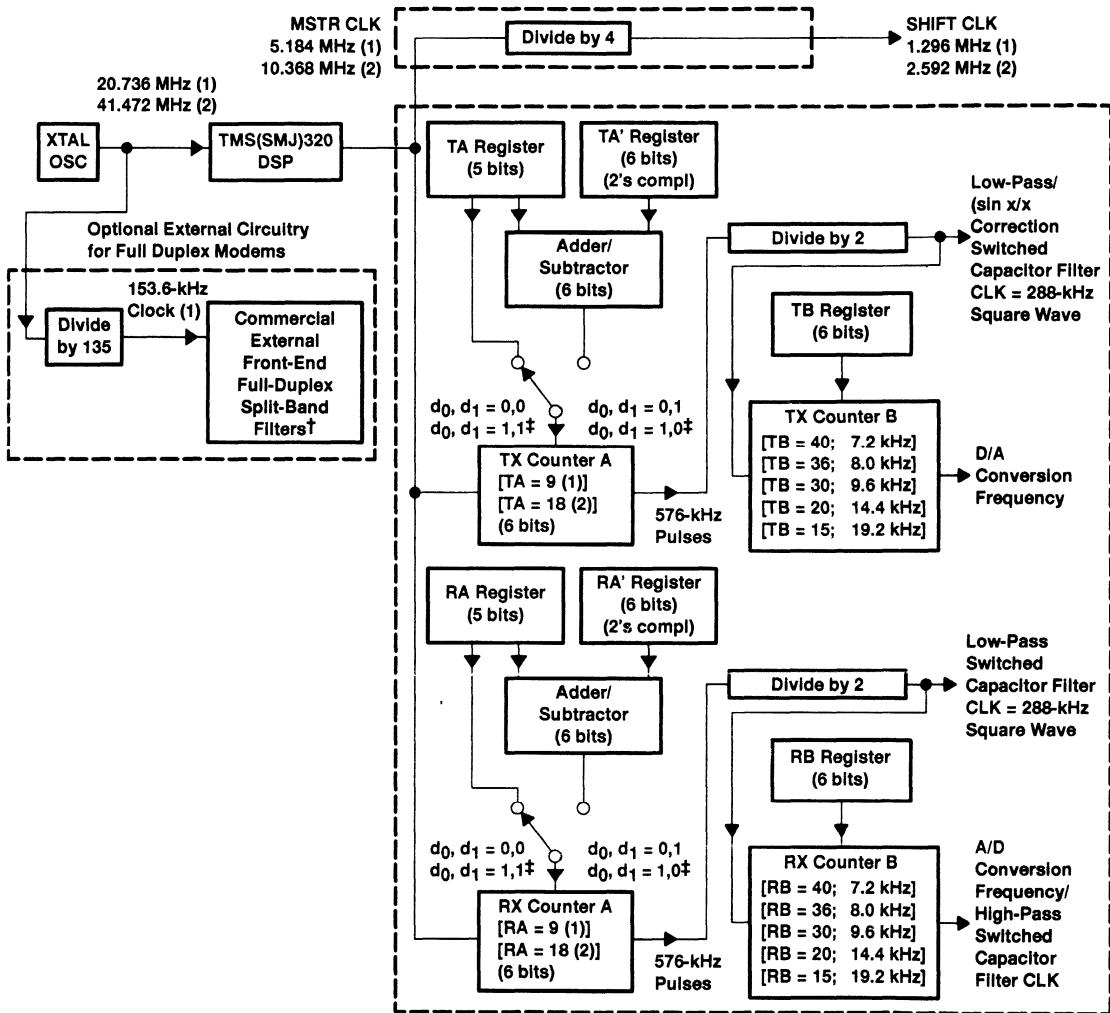
loopback

This feature allows the user to test the circuit remotely. In loopback, OUT+ and OUT- are internally connected to the IN+ and IN-. Thus, the DAC bits (d15 to d2), which are transmitted to DX, can be compared with the ADC bits (d15 to d2), which are received from DR. An ideal comparison would be that the bits on DR equal the bits on DX. However, there are some difference in these bits due to the ADC and DAC output offsets. The loopback feature is implemented with digital signal processor control by transmitting the appropriate serial port bit to the control register (see AIC DX data word format section).

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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INTERNAL TIMING CONFIGURATION



† Split-band filtering can alternatively be performed after the analog input function via software in the TMS(SMJ)320.

‡ These control bits are described in the AIC DX data word format section.

NOTE: Frequency 1 (20.736 MHz) is used to show how 153.6 kHz (for a commercially available modem split-band filter clock), popular speech and modem sampling signal frequencies, and an internal 288-kHz switched-capacitor filter clock can be derived synchronously and as submultiples of the crystal oscillator frequency. Since these derived frequencies are synchronous submultiples of the crystal frequency, aliasing does not occur as the sampled analog signal passes between the analog converter and switched-capacitor filter stages. Frequency 2 (41.472 MHz) is used to show that the AIC can work with high-frequency signals, which are used by high-speed digital signal processors.

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explanation of internal timing configuration

All of the internal timing of the AIC is derived from the high-frequency clock signal that drives the master clock input. The shift clock signal, which strobes the serial port data between the AIC and DSP, is derived by dividing the master clock input signal frequency by four.

Low-pass:

$$\text{SCF Clock Frequency (D/A or A/D path)} = \frac{\text{Master Clock Frequency}}{2 \times \text{Contents of Counter A}}$$

$$\text{Conversion Frequency} = \frac{\text{SCF Clock Frequency (D/A or A/D path)}}{\text{Contents of Counter B}}$$

High-pass:

$$\text{SCF Clock Frequency (A/D Path)} = \text{A/D Conversion Frequency}$$

$$\text{Shift Clock Frequency} = \frac{\text{Master Clock Frequency}}{4}$$

TX counter A and TX counter B, which are driven by the master clock, determine the D/A conversion timing. Similarly, RX counter A and RX counter B determine the A/D conversion timing. In order for the low-pass switched-capacitor filter in the D/A path to meet its transfer function specifications, the frequency of its clock input must be 288 kHz. If the clock frequency is not 288 kHz, the filter transfer function frequencies are frequency-scaled by the ratios of the clock frequency to 288 kHz. Thus, to obtain the specified filter response, the combination of master clock frequency and TX counter A and RX counter A values must yield a 288-kHz switched-capacitor clock signal. This 288-kHz clock signal can then be divided by the TX counter B to establish the D/A conversion timing.

The transfer function of the bandpass switched-capacitor filter in the A/D path is a composite of its high-pass and low-pass section transfer functions. The high-frequency roll-off of the low-pass section meets the bandpass filter transfer function specification when the low-pass section SCF is 288 kHz. Otherwise, the high-frequency roll-off will be frequency-scaled by the ratio of the high-pass section's SCF clock to 288 kHz. The low-frequency roll-off of the high-pass section meets the bandpass filter transfer function specification when the A/D conversion rate is 8 kHz. Otherwise, the low-frequency roll-off of the high-pass section is frequency-scaled by the ratio of the A/D conversion rate to 8 kHz.

TX counter A and TX counter B are reloaded every D/A conversion period, while RX counter A and RX counter B are reloaded every A/D conversion period. The TX counter B and RX counter B are loaded with the values in the TB and RB registers, respectively. Via software control, the TX counter A can be loaded with either the TA register, the TA register less the TA' register, or the TA register plus the TA' register. By selecting the TA register less the TA' register option, the upcoming conversion timing occurs earlier by an amount of time that equals TA' times the signal period of the master clock. By selecting the TA register plus the TA' register option, the upcoming conversion timing occurs later by an amount of time that equals TA' times the signal period of the master clock. The D/A conversion timing can be advanced or retarded. An identical ability to alter the A/D conversion timing is provided. In this case, however, the RX counter A can be programmed via software control with the RA register, the RA register less the RA' register, or the RA register plus the RA' register.

The ability to advance or retard conversion timing is particularly useful for modem applications. This feature allows controlled changes in the A/D and D/A conversion timing. This feature can be used to enhance signal-to-noise performance, to perform frequency-tracking functions, and to generate nonstandard modem frequencies.

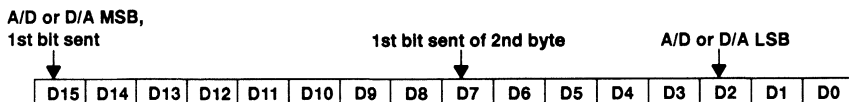
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explanation of internal timing configuration (continued)

If the transmit and receive sections are configured to be synchronous (see WORD/BYTE description), then both the low-pass and bandpass switched-capacitor filter clocks are derived from TX counter A. Also, both the D/A and A/D conversion timing are derived from the TX counter A and TX counter B. When the transmit and receive sections are configured to be synchronous, the RX counter A, RX counter B, RA register, RA' register, and RB registers are not used.

AIC DR or DX word bit pattern



AIC DX data word format section

d15	d14	d13	d12	d11	d10	d9	d8	d7	d6	d5	d4	d3	d2	d1	d0	Comments	
primary DX serial communication protocol																	
←d15 (MSB) through d2 go to the D/A converter register														→	0	0	The TX and RX counter As are loaded with the TA and RA register values. The TX and RX counter Bs are loaded with TB and RB register values.
←d15 (MSB) through d2 go to the D/A converter register														→	0	1	The TX and RX counter As are loaded with the TA + TA' and RA + RA' register values. The TX and RX counter Bs are loaded with the TB and RB register values. LSBs d1 = 0 and d0 = 1 cause the next D/A and A/D conversion periods to be changed by the addition of TA' and RA' master clock cycles, in which TA' and RA' can be positive or negative or zero (refer to Table 1).
←d15 (MSB) through d2 go to the D/A converter register														→	1	0	The TX and RX counter As are loaded with the TA - TA' and RA - RA' register values. The TX and RX counter Bs are loaded with the TB and RB register values. LSBs d1 = 1 and d0 = 0 cause the next D/A and A/D conversion periods to be changed by the subtraction of TA' and RA' master clock cycles, in which TA' and RA' can be positive or negative or zero (refer to Table 1).
←d15 (MSB) through d2 go to the D/A converter register														→	1	1	The TX and RX counter As are loaded with the TA and RA register converter register values. The TX and RX counter Bs are loaded with the TB and RB register values. After a delay of four shift clock cycles, a secondary transmission immediately follows to program the AIC to operate in the desired configuration.

NOTE: Setting the two least significant bits to 1 in the normal transmission of DAC information (primary communications) to the AIC initiates secondary communications upon completion of the primary communications. Upon completion of the primary communication, FSR remains high for four shift clock cycles and then goes low and initiates the secondary communication. The timing specifications for the primary and secondary communications are identical. In this manner, the secondary communication, if initiated, is interleaved between successive primary communications. This interleaving prevents the secondary communication from interfering with the primary communications and DAC timing, thus preventing the AIC from skipping a DAC output. In the synchronous mode, FSR is not asserted during secondary communications.



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secondary DX serial communication protocol

$x\ x\ \leftarrow$ to TA register \rightarrow $x\ x\ \leftarrow$ to RA register \rightarrow	0 0	d13 and d6 are MSBs (unsigned binary)
$x\ \leftarrow$ to TA' register \rightarrow $x\ \leftarrow$ to RA' register \rightarrow	0 1	d14 and d7 are 2's complement sign bits
$x\ \leftarrow$ to TB register \rightarrow $x\ \leftarrow$ to RB register \rightarrow	1 0	d14 and d7 are MSBs (unsigned binary)
$x\ x\ x\ x\ x\ x\ x\ d9$ $x\ d7\ d6\ d5\ d4\ d3\ d2\ 1\ 1$		
		<p>d2 = 0/1 deletes/inserts the A/D high-pass filter</p> <p>d3 = 0/1 disables/enables the loopback function</p> <p>d4 = 0/1 disables/enables the AUX IN+ and AUX IN-</p> <p>d5 = 0/1 asynchronous/synchronous transmit and receive sections</p> <p>d6 = 0/1 gain control bits (see gain control section)</p> <p>d7 = 0/1 gain control bits (see gain control section)</p> <p>d9 = 0/1 delete/insert on-board second-order (sin x)/x correction filter</p>

reset function

A reset function is provided to initiate serial communications between the AIC and DSP. The reset function initializes all AIC registers, including the control register. After power has been applied to the AIC, a negative-going pulse on $\overline{\text{RESET}}$ initializes the AIC registers to provide an 8-kHz A/D and D/A conversion rate for a 5.184 MHz master clock input signal. The AIC, except the control register, is initialized as follows (see AIC DX data word format section):

REGISTER	INITIALIZED REGISTER VALUE (HEX)
TA	9
TA'	1
TB	24
RA	9
RA'	1
RB	24

The control register bits are reset as follows (see AIC DX data word format section):

$$d9 = 1, d7 = 1, d6 = 1, d5 = 1, d4 = 0, d3 = 0, d2 = 1$$

This initialization allows normal serial port communications to occur between AIC and DSP. If the transmit and receive sections are configured to operate synchronously and the user wishes to program different conversion rates, only the TA, TA', and TB register need to be programmed, since both transmit and receive timing are synchronously derived from these registers (see the terminal functions table and AIC DX word format sections).

The circuit shown in Figure 1 provides a reset on power up when power is applied in the sequence given under power-up sequence. The circuit depends on the power supplies reaching their recommended values a minimum of 800 ns before the capacitor charges to 0.8 V above DGTL GND.

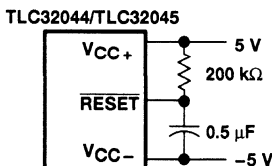


Figure 1. Power-Up Reset

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power-up sequence

To ensure proper operation of the AIC and as a safeguard against latch-up, it is recommended that Schottky diodes with forward voltages less than or equal to 0.4 V be connected from V_{CC-} to ANLG GND and from V_{CC-} to DGTL GND (see Figure 21). In the absence of such diodes, power should be applied in the following sequence: ANLG GND and DGTL GND, V_{CC-} , then V_{CC+} and V_{DD} . Also, no input signal should be applied until after power up.

AIC responses to improper conditions

The AIC has provisions for responding to improper conditions. These improper conditions and the response of the AIC to these conditions are presented in Table 1 below.

AIC register constraints

The following constraints are placed on the contents of the AIC registers:

1. TA register must be ≥ 4 in word mode ($WORD/BYTE = \text{high}$).
2. TA register must be ≥ 5 in byte mode ($WORD/BYTE = \text{low}$).
3. TA' register can be either positive, negative, or zero.
4. RA register must be ≥ 4 in word mode ($WORD/BYTE = \text{high}$).
5. RA register must be ≥ 5 in byte mode ($WORD/BYTE = \text{low}$).
6. RA' register can be either positive, negative, or zero.
7. (TA register \pm TA' register) must be > 1 .
8. (RA register \pm RA' register) must be > 1 .
9. TB register must be > 1 .

Table 1. AIC Responses to Improper Conditions

IMPROPER CONDITION	AIC RESPONSE
TA register + TA' register = 0 or 1 TA register - TA' register = 0 or 1	Reprogram TX counter A with TA register value
TA register + TA' register < 0	MODULO 64 arithmetic is used to ensure that a positive value is loaded into the TX counter A, i.e., TA register + TA' register + 40 hex is loaded into TX counter A.
RA register + RA' register = 0 or 1 RA register - RA' register = 0 or 1	Reprogram RX counter A with RA register value
RA register + RA' register = 0 or 1	MODULO 64 arithmetic is used to ensure that a positive value is loaded into RX counter A, i.e., RA register + RA' register + 40 hex is loaded into RX counter A.
TA register = 0 or 1 RA register = 0 or 1	AIC is shut down.
TA register < 4 in word mode TA register < 5 in byte mode RA register < 4 in word mode RA register < 5 in byte mode	The AIC serial port no longer operates.
TB register = 0 or 1	Reprogram TB register with 24 hex
RB register = 0 or 1	Reprogram RB register with 24 hex
AIC and DSP cannot communicate	Hold last DAC output

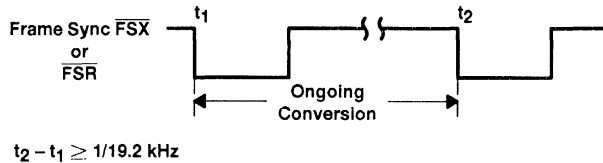
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improper operation due to conversion times being too close together

If the difference between two successive D/A conversion frame syncs is less than 1/19.2 kHz, the AIC operates improperly. In this situation, the second D/A conversion frame sync occurs too quickly and there is not enough time for the ongoing conversion to be completed. This situation can occur if the A and B registers are improperly programmed or if the A + A' register or A - A' register result is too small. When incrementally adjusting the conversion period via the A + A' register options, the designer should be careful not to violate this requirement (see following diagram).



asynchronous operation — more than one receive frame sync occurring between two transmit frame syncs

When incrementally adjusting the conversion period via the A + A' or A - A' register options, a specific protocol is followed. The command to use the incremental conversion period adjust option is sent to the AIC during a $\overline{\text{FSX}}$ frame sync. The ongoing conversion period is then adjusted. However, either receive conversion period A or B can be adjusted. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. Therefore, if there is sufficient time between t_1 and t_2 , the receive conversion period adjustment is performed during receive conversion period A. Otherwise, the adjustment is performed during receive conversion period B. The adjustment command only adjusts one transmit conversion period and one receive conversion period. To adjust another pair of transmit and receive conversion periods, another command must be issued during a subsequent $\overline{\text{FSX}}$ frame (see figure below).

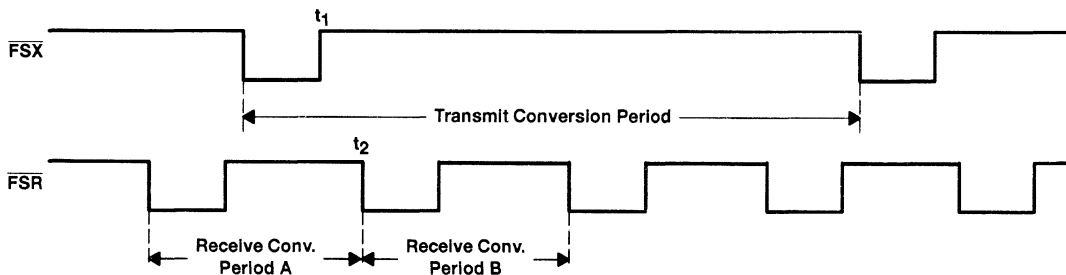


Figure 2. Adjusted Transmit and Receive Conversion Periods

asynchronous operation — more than one transmit frame sync occurring between two receive frame syncs

When incrementally adjusting the conversion period via the A + A' or A - A' register options, a specific protocol is followed. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. The command to use the incremental conversion period adjust options is sent to the AIC during a $\overline{\text{FSX}}$ frame sync. The ongoing transmit conversion period is then adjusted. However, three possibilities exist for the receive conversion period adjustment in the diagram as shown in the following figure. If the adjustment command is issued during transmit conversion period A, receive conversion period A is adjusted if there is sufficient time between t_1 and t_2 . If there is not sufficient time between t_1 and t_2 , receive conversion period B is adjusted. The receive portion of an adjustment command can be ignored if the adjustment command is sent during a receive conversion period, which is already being or will be adjusted

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due to a prior adjustment command. For example, if adjustment commands are issued during transmit conversion periods A, B, and C, the first two commands can cause receive conversion periods A and B to be adjusted, while the third receive adjustment command is ignored. The third adjustment command is ignored since it was issued during receive conversion period B, which already is adjusted via the transmit conversion period B adjustment command.

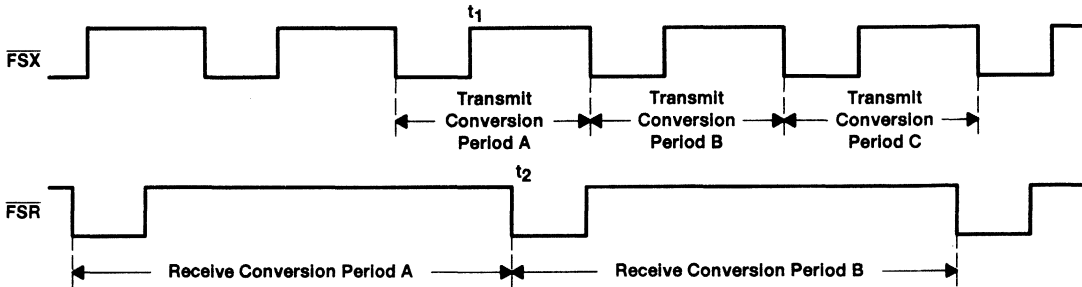


Figure 3. Receive and Transmit Conversion Period Adjustments

asynchronous operation — more than one set of primary and secondary DX serial communication occurring between two receive frame sync (see AIC DX data word format section)

The TA, TA', TB, and control register information that is transmitted in the secondary communications is always accepted and is applied during the ongoing transmit conversion period. If there is sufficient time between t_1 and t_2 , the TA, RA', and RB register information, which is sent during transmit conversion period A, is applied to receive conversion period A. Otherwise, this information is applied during receive conversion period B. If RA, RA', and RB register information has already been received and is being applied during an ongoing conversion period, any subsequent RA, RA', or RB information that is received during this receive conversion period is disregarded (see Figure 4).

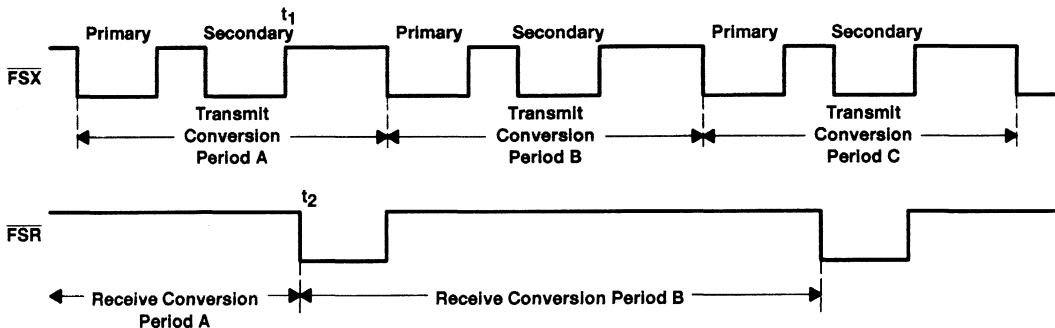


Figure 4. Receive and Transmit Periods for Primary and Secondary Data

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test modes†

The TLC32044 or TLC32045 can be operated in special test modes. These test modes are used by Texas Instruments to facilitate testing of the device during manufacturing. They are not intended to be used in real applications, however, they allow the filters in the A/D and D/A paths to be used without using the A/D and D/A converters.

In normal operation, the nonusable (NU) terminals are left unconnected. These NU terminals are used by the factory to speed up testing of the TLC32044 or TLC32045 analog interface circuits (AIC). When the device is used in normal (non-test mode) operation, the NU terminal (terminal 1) has an internal pulldown to -5 V. Externally connecting 0 V or 5 V to terminal 1 puts the device in test-mode operation. Selecting one of the possible test modes is accomplished by placing a particular voltage on certain terminals. A description of these modes is provided in Table 2 and Figures 5 and 6.

Table 2. List of Test Modes

TEST TERMINALS	D/A PATH TEST (TERMINAL 1 to 5 V)	A/D PATH TEST (TERMINAL 1 to 0)
	TEST FUNCTION	TEST FUNCTION
5	The low-pass switched-capacitor filter clock is brought out to DR. This clock signal is normally internal.	The bandpass switched-capacitor filter clock is brought out to DR. This clock signal is normally internal.
11	No change from normal operation. The \overline{EODX} signal is brought out to \overline{EODX} .	The pulse that initiates the A/D conversion is brought out here. This signal is normally internal.
3	The pulse that initiates the D/A conversion is brought out here.	No change from normal operation. The \overline{EODR} signal is brought out.
27 and 28	There are no test output signals provided on these terminals.	The outputs of the A/D path low-pass or bandpass filter (depending upon control bit d2 – see AIC DX data word format section) are brought out to these terminals. If the high-pass section is inserted, the output will have a $(\sin x)/x$ droop. The slope of the droop is determined by the ADC sampling frequency, which is the high-pass section clock frequency (see diagram of bandpass or low-pass filter test for receive section). These outputs drive small (30-pF) loads.
15 and 16	D/A PATH LOW-PASS FILTER TEST; (WORD/BYTE) to -5 V	
	TEST FUNCTION	
	The inputs of the D/A path low-pass filter are brought out to terminals 15 and 16. The D/A input to this filter is removed. If $(\sin x)/x$ correction filter is inserted, the OUT + and OUT – signals have a flat response (see Figure 2). The common-mode range of these inputs must not exceed ± 0.5 V.	

† In the test mode, the AIC responds to the setting of WORD/BYTE to -5 V, as if WORD/BYTE were set to 0 V. Thus, the byte mode is selected for communicating between DSP and AIC. Either of the path tests (D/A or A/D) can be performed simultaneously with the D/A low-pass filter test. In this situation, WORD/BYTE must be connected to -5 V, which initiates byte-mode communications.

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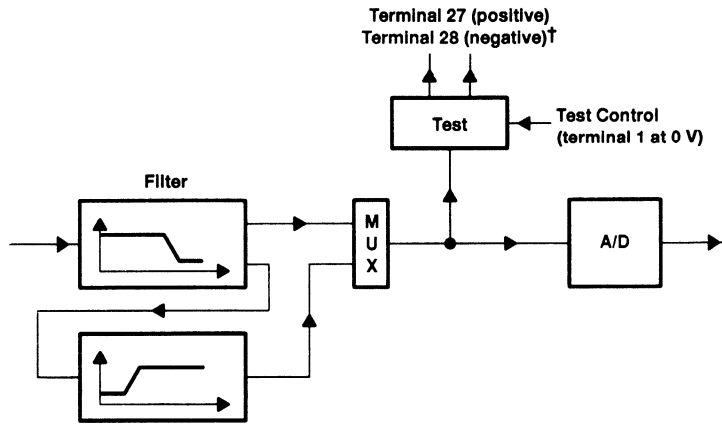


Figure 5. Bandpass or Low-Pass Filter Test for Receiver Section

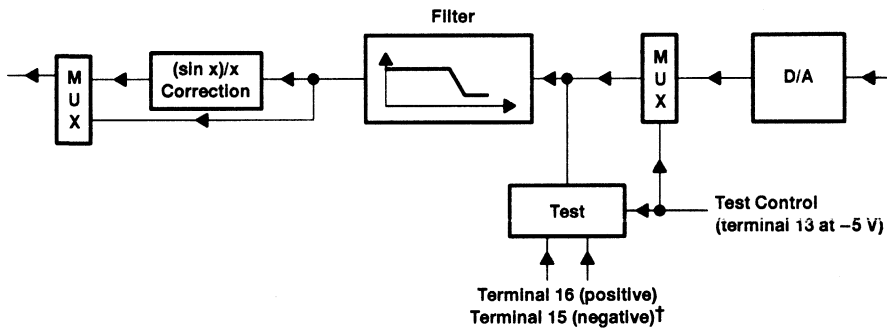


Figure 6. Low-Pass Filter Test for Transmit Section

† All analog signal paths have differential architecture and hence have positive and negative components.

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V_{CC+} (see Note 1)	–0.3 V to 15 V
Supply voltage range, V_{DD}	–0.3 V to 15 V
Output voltage range, V_O	–0.3 V to 15 V
Input voltage range, V_I	–0.3 V to 15 V
Digital ground voltage range	–0.3 V to 15 V
Operating free-air temperature range: TLC32044C, TLC32045C	0°C to 70°C
TLC32044E	–20°C to 85°C
TLC32044I, TLC32045I	–40°C to 85°C
TLC32044M	–55°C to 125°C
Storage temperature range: TLC32044C, I, TLC32045C, I	–40°C to 125°C
TLC32044M	–65°C to 150°C
Case temperature for 10 seconds: FN or FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	260°C
J package	300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Voltage values for maximum ratings are with respect to V_{CC-} .

recommended operating conditions

	MIN	NOM	MAX	UNIT	
Supply voltage, V_{CC+} (see Note 2)	4.75	5	5.25	V	
Supply voltage, V_{CC-} (see Note 2)	–4.75	–5	–5.25	V	
Digital supply voltage, V_{DD} (see Note 2)	4.75	5	5.25	V	
Digital ground voltage with respect to ANLG GND, DGTL GND		0		V	
Reference input voltage, $V_{ref(ext)}$ (see Note 2)	2		4	V	
High-level input voltage, V_{IH}	2		$V_{DD} + 0.3$	V	
Low-level input voltage, V_{IL} (see Note 3)	–0.3		0.8	V	
Load resistance at OUT+ and/or OUT–, R_L		300		Ω	
Load capacitance at OUT+ and/or OUT–, C_L			100	pF	
MSTR CLK frequency (see Note 4)	0.075	5	10.368	MHz	
Analog input amplifier common mode input voltage (see Note 5)			± 1.5	V	
A/D or D/A conversion rate			20	kHz	
Operating free-air temperature, T_A	TLC32044C, TLC32045C		0	70	°C
	TLC32044E		–20	85	
	TLC32044I, TLC32045I		–40	85	
	TLC32044M		–55	125	

NOTES: 2. Voltages at analog inputs and outputs, REF, V_{CC+} , and V_{CC-} , are with respect to the ANLG GND terminal. Voltages at digital inputs and outputs and V_{DD} are with respect to the DGTL GND terminal.

- The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data sheet for logic voltage levels and temperature only.
- The bandpass switched-capacitor filter (SCF) specifications apply only when the low-pass section SCF clock is 288 kHz and the high-pass section SCF clock is 8 kHz. If the low-pass SCF clock is shifted from 288 kHz, the low-pass roll-off frequency will shift by the ratio of the low-pass SCF clock to 288 kHz. If the high-pass SCF is shifted from 8 kHz, the high-pass roll-off frequency will shift by the ratio of the high-pass SCF clock to 8 kHz. Similarly, the low-pass switched-capacitor filter (SCF) specifications apply only when the SCF clock is 288 kHz. If the SCF clock is shifted from 288 kHz, the low-pass roll-off frequency will shift by the ratio of the SCF clock to 288 kHz.
- This range applies when (IN+ – IN–) or (AUX IN+ – AUX IN–) equals ± 6 V.



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electrical characteristics over recommended operating free-air temperature range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

total device, MSTR CLK frequency = 5.184 MHz, outputs not loaded

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$V_{DD} = 4.75\text{ V}$, $I_{OH} = -300\text{ }\mu\text{A}$	2.4			V
V_{OL}	Low-level output voltage	$V_{DD} = 4.75\text{ V}$, $I_{OL} = 2\text{ mA}$			0.4	
I_{CC+}	Supply current from V_{CC+}	TLC32044C, TLC32045C			35	mA
		TLC32044I, TLC32045I, TLC32044E, TLC32044M			40	
I_{CC-}	Supply current from V_{CC-}	TLC32044C, TLC32045C			-35	
		TLC32044I, TLC32045I, TLC32044E, TLC32044M			-40	
I_{DD}	Supply current from V_{DD}	TLC3204xC, E, I	$f_{MSTR\ CLK} = 5.184\text{ MHz}$		7	
		TLC32044M			8	
V_{ref}	Internal reference output voltage	TLC3204xC, E, I		3	3.3	V
		TLC32044M		2.9	3.3	
αV_{ref}	Temperature coefficient of internal reference voltage			200		ppm/°C
r_o	Output resistance at REF			100		k Ω

receive amplifier input

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
A/D converter offset error (filters in)	TLC32044C, E, I			10	70	mV
	TLC32044M			10	85	
	TLC32045C, I			10	75	
CMRR	Common-mode rejection ratio at $IN+$, $IN-$, or $AUX\ IN+$, $AUX\ IN-$	TLC3204xC, E, I	See Note 6		55	dB
		TLC32044M			35	
r_i	Input resistance at $IN+$, $IN-$, or $AUX\ IN+$, $AUX\ IN-$, REF			100		k Ω

transmit filter output

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OO}	Output offset voltage at $OUT+$ or $OUT-$ (single-ended relative to ANLG GND)	TLC3204xC, E, I		15	80	mV
		TLC32044M		15	75	
V_{OM}	Maximum peak output voltage swing across R_L at $OUT+$ or $OUT-$ (single ended)	$R_L \geq 300\text{ }\Omega$, Offset voltage = 0		± 3		V
V_{OM}	Maximum peak output voltage swing between $OUT+$ and $OUT-$ (differential output)	$R_L \geq 600\text{ }\Omega$		± 6		

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 6: The test condition is a 0-dBm, 1-kHz input signal with an 8-kHz conversion rate.

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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system distortion specifications, SCF clock frequency = 288 kHz (see Note 7)

PARAMETER			TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Attenuation of second harmonic of A/D input signal	Single ended	TLC3204xC, E, I	$V_I = -0.5 \text{ dB to } -24 \text{ dB referred to } V_{ref}$ $T_A = 25^\circ\text{C}$	70		dB	
		TLC32044M		62	70		
	Differential	TLC32044C, E, I	$V_I = -0.5 \text{ dB to } -24 \text{ dB referred to } V_{ref}$	62	70		
		TLC32045C, I		55	70		
Attenuation of third and higher harmonics of A/D input signal	Single ended	TLC3204xC, E, I	$V_I = -0.5 \text{ dB to } -24 \text{ dB referred to } V_{ref}$ $T_A = 25^\circ\text{C}$	65			
		TLC32044M		57	65		
	Differential	TLC32044C, E, I	$V_I = -0.5 \text{ dB to } -24 \text{ dB referred to } V_{ref}$	57	65		
		TLC32045C, I		55	65		
Attenuation of second harmonic of D/A input signal	Single ended	TLC3204xC, I, M	$V_I = -0 \text{ dB to } -24 \text{ dB referred to } V_{ref}$	70			
	Differential	TLC32044C, E, I		62	70		
		TLC32045C, I		55	70		
Attenuation of third and higher harmonics of D/A input signal	Single ended	TLC3204xC, I, M	$V_I = -0 \text{ dB to } -24 \text{ dB referred to } V_{ref}$	65			
	Differential	TLC32044C, E, I		57	65		
		TLC32045C, I		55	65		

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 7: The test condition V_I is a 1-kHz input signal with an 8-kHz conversion rate (0 dB relative to V_{ref}). The load impedance for the DAC is 600 Ω (300 Ω for TLC32044M).



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A/D channel signal-to-distortion ratio (see Note 7)

PARAMETER	TEST CONDITIONS	$A_V = 1^\dagger$		$A_V = 2^\ddagger$		$A_V = 4^\ddagger$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
A/D channel signal-to-distortion ratio, TLC32044C, TLC32044I, TLC32044E	$V_I = -6 \text{ dB to } -0.1 \text{ dB}$	58		>58 [‡]		>58 [‡]		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	58		58		>58 [‡]		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	56		58		58		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	50		56		58		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	44		50		56		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	38		44		50		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	32		38		44		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	26		32		38		
	$V_I = -54 \text{ dB to } -48 \text{ dB}$	20		26		32		
A/D channel signal-to-distortion ratio, TLC32044M	$V_I = -6 \text{ dB to } -0.5 \text{ dB}$	58		>58 [‡]		>58 [‡]		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	58		58		>58 [‡]		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	56		58		58		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	50		56		58		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	44		50		56		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	38		44		50		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	32		38		44		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	26		32		38		
	$V_I = -54 \text{ dB to } -48 \text{ dB}$	20		26		32		
A/D channel signal-to-distortion ratio, TLC32045C, TLC32045I	$V_I = -6 \text{ dB to } -0.1 \text{ dB}$	55		>55 [‡]		>55 [‡]		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	55		55		>55 [‡]		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	53		55		55		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	47		53		55		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	41		47		53		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	35		41		47		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	29		35		41		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	23		29		35		
	$V_I = -54 \text{ dB to } -48 \text{ dB}$	17		23		29		

[†] A_V is the programmable gain of the input amplifier.

[‡] A value >60 is over range and signal clipping occurs.

NOTE 7: The test condition V_I is a 1-kHz input signal with an 8-kHz conversion rate (0 dB relative to V_{ref}). The load impedance for the DAC is 600 Ω (300 Ω for TLC32044M).

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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D/A channel signal-to-distortion ratio (see Note 7)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
D/A channel signal-to-distortion ratio, TLC32044C, TLC32044E, TLC32044I, TLC32044M	$V_I = -6$ dB to 0 dB	58		dB
	$V_I = -12$ dB to -6 dB	58		
	$V_I = -18$ dB to -12 dB	56		
	$V_I = -24$ dB to -18 dB	50		
	$V_I = -30$ dB to -24 dB	44		
	$V_I = -36$ dB to -30 dB	38		
	$V_I = -42$ dB to -36 dB	32		
	$V_I = -48$ dB to -42 dB	26		
	$V_I = -54$ dB to -48 dB	20		
D/A channel signal-to-distortion ratio, TLC32045C, TLC32045I	$V_I = -6$ dB to 0 dB	55		
	$V_I = -12$ dB to -6 dB	55		
	$V_I = -18$ dB to -12 dB	53		
	$V_I = -24$ dB to -18 dB	47		
	$V_I = -30$ dB to -24 dB	41		
	$V_I = -36$ dB to -30 dB	35		
	$V_I = -42$ dB to -36 dB	29		
	$V_I = -48$ dB to -42 dB	23		
	$V_I = -54$ dB to -48 dB	17		

NOTE 7: The test condition V_I is a 1-kHz input signal with an 8-kHz conversion rate (0 dB relative to V_{REF}). The load impedance for the DAC is 600 Ω (300 Ω for TLC32044M).

gain and dynamic range

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Absolute transmit gain tracking error while transmitting into 600 Ω	-48 -dB to 0-dB signal range, See Note 8		± 0.05	± 0.15	dB
Absolute transmit gain tracking error while transmitting into 300 Ω , TLC32044M	-48 -dB to 0-dB signal range, $T_A = 25^\circ\text{C}$, See Note 8		± 0.05	± 0.25	dB
Absolute transmit gain tracking error while transmitting into 300 Ω , TLC32044M	-48 -dB to 0-dB signal range, $T_A = -55^\circ\text{C}$ to 125°C , See Note 8			± 0.4	dB
Absolute receive gain tracking error	-48 -dB to 0-dB signal range, See Note 8		± 0.05	± 0.15	dB
Absolute receive gain tracking error, TLC32044M	-48 -dB to 0-dB signal range, $T_A = 25^\circ\text{C}$, See Note 8		± 0.05	± 0.25	dB
Absolute receive gain tracking error, TLC32044M	-48 -dB to 0-dB signal range, $T_A = -55^\circ\text{C}$ to 125°C , See Note 8			± 0.4	dB
Absolute gain of the A/D channel	Signal input is a -0.5 -dB, 1-kHz sinewave		0.2		dB
Absolute gain of the D/A channel	Signal input is a 0-dB, 1-kHz sinewave		-0.3		

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 8: Gain tracking is relative to the absolute gain at 1 kHz and 0 dB (0 dB relative to V_{REF}).



TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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power supply rejection and crosstalk attenuation

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{CC+} or V _{CC-} supply voltage rejection ratio, receive channel	f = 0 to 30 kHz	Idle channel, supply signal at 200 mV		30		dB
	f = 30 kHz to 50 kHz	p-p measured at DR (ADC output)		45		
V _{CC+} or V _{CC-} supply voltage rejection ratio, transmit channel (single ended)	f = 0 to 30 kHz	Idle channel, supply signal at 200 mV		30		
	f = 30 kHz to 50 kHz	p-p measured at OUT +		45		
Crosstalk attenuation, transmit-to-receive (single ended)	TLC3204xC, E, I			80		
	TLC32044M		65	80		
Crosstalk attenuation, receive-to-transmit, TLC32044M		Inputs grounded, Gain = 1, 2, 4	65			

† All typical values are at T_A = 25°C.

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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delay distortion

bandpass filter transfer function, SCF $f_{\text{clock}} = 288 \text{ kHz}$ IN+ – IN– is a $\pm 3 \text{ V}$ sinewave† (see Note 9)

PARAMETER	TEST CONDITIONS	FREQUENCY RANGE	ADJUSTMENT ADDEND‡	MIN	TYP§	MAX	UNIT
Filter gain, TLC32044C, TLC32044E, TLC32044I	Input signal reference to 0 dB	$f \leq 50 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-33	-29	-25	dB
		$f = 100 \text{ Hz}$	$K1 \times -0.26 \text{ dB}$	-4	-2	-1	
		$f = 150 \text{ Hz to } 3100 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	
		$f = 3100 \text{ Hz to } 3300 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		$f = 3300 \text{ Hz to } 3650 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		$f = 3800 \text{ Hz}$	$K1 \times 2.3 \text{ dB}$		-3	-1	
		$f = 4000 \text{ Hz}$	$K1 \times 2.7 \text{ dB}$		-17	-16	
		$f \geq 5000 \text{ Hz}$	$K1 \times 0 \text{ dB}$			-65	
Filter gain, TLC32044M	Input signal reference to 0 dB	$f \leq 50 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-33	-29	-25	dB
		$f = 100 \text{ Hz}$	$K1 \times -0.26 \text{ dB}$	-4	-2	-1	
		$f = 150 \text{ Hz to } 3100 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	
		$f = 3100 \text{ Hz to } 3300 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		$f = 3300 \text{ Hz to } 3500 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		$f = 3800 \text{ Hz}$	$K1 \times 2.3 \text{ dB}$		-3	-0.5	
		$f = 4000 \text{ Hz}$	$K1 \times 2.7 \text{ dB}$		-17	-16	
		$f \geq 5000 \text{ Hz}$	$K1 \times 0 \text{ dB}$			-65	
Filter gain, TLC32045C, TLC32045I	Input signal reference to 0 dB	$f \leq 50 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-33	-29	-25	dB
		$f = 100 \text{ Hz}$	$K1 \times -0.26 \text{ dB}$	-4	-2	-1	
		$f = 150 \text{ Hz to } 3100 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	
		$f = 3100 \text{ Hz to } 3300 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		$f = 3300 \text{ Hz to } 3650 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		$f = 3800 \text{ Hz}$	$K1 \times 2.3 \text{ dB}$		-3	-1	
		$f = 4000 \text{ Hz}$	$K1 \times 2.7 \text{ dB}$		-17	-16	
		$f \geq 5000 \text{ Hz}$	$K1 \times 0 \text{ dB}$			-65	

† See filter curves in typical characteristics

‡ The MIN, TYP, and MAX specifications are given for a 288-kHz SCF clock frequency. A slight error in the 288-kHz SCF may result from inaccuracies in the MSTR CLK frequency, resulting from crystal frequency tolerances. If this frequency error is less than 0.25%, the ADJUSTMENT ADDEND should be added to the MIN, TYP, and MAX specifications, where $K1 = 100 \cdot [(SCF \text{ frequency} - 288 \text{ kHz}) / 288 \text{ kHz}]$. For errors greater than 0.25%, see Note 8.

§ All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 9: The filter gain outside of the passband is measured with respect to the gain at 1 kHz. The filter gain within the passband is measured with respect to the average gain within the passband. The passbands are 150 to 3600 Hz and 0 to 3600 Hz for the bandpass and low-pass filters respectively. For switched-capacitor filter clocks at frequencies other than 288 kHz, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 288 kHz.



TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I

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low-pass filter transfer function†, SCF $f_{\text{clock}} = 288 \text{ kHz}$ (see Note 9)

PARAMETER	TEST CONDITIONS	FREQUENCY RANGE	ADJUSTMENT ADDEND‡	MIN	TYP§	MAX	UNIT
Filter gain, TLC32044C, TLC32044E, TLC32044I	Input signal reference is 0 dB	f = 0 Hz to 3100 Hz	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	dB
		f = 3100 Hz to 3300 Hz	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		f = 3300 Hz to 3650 Hz	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		f = 3800 Hz	$K1 \times 2.3 \text{ dB}$		-3	-1	
		f = 4000 Hz	$K1 \times 2.7 \text{ dB}$		-17	-16	
		f ≥ 4400 Hz	$K1 \times 3.2 \text{ dB}$			-40	
		f ≥ 5000 Hz	$K1 \times 0 \text{ dB}$			-65	
Filter gain, TLC32044M	Input signal reference is 0 dB	f = 0 Hz to 3100 Hz	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	dB
		f = 3100 Hz to 3300 Hz	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		f = 3300 Hz to 3500 Hz	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		f = 3800 Hz	$K1 \times 2.3 \text{ dB}$		-3	-0.5	
		f = 4000 Hz	$K1 \times 2.7 \text{ dB}$		-17	-16	
		f ≥ 4400 Hz	$K1 \times 3.2 \text{ dB}$			-40	
		f ≥ 5000 Hz	$K1 \times 0 \text{ dB}$			-65	
Filter gain, TLC32045C, TLC32045I	Input signal reference is 0 dB	f = 0 Hz to 3100 Hz	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	dB
		f = 3100 Hz to 3300 Hz	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		f = 3300 Hz to 3650 Hz	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		f = 3800 Hz	$K1 \times 2.3 \text{ dB}$		-3	-1	
		f = 4000 Hz	$K1 \times 2.7 \text{ dB}$		-17	-16	
		f ≥ 4400 Hz	$K1 \times 3.2 \text{ dB}$			-40	
		f ≥ 5000 Hz	$K1 \times 0 \text{ dB}$			-65	

† See filter curves in typical characteristics

‡ The MIN, TYP, and MAX specifications are given for a 288-kHz SCF clock frequency. A slight error in the 288-kHz SCF may result from inaccuracies in the MSTR CLK frequency, resulting from crystal frequency tolerances. If this frequency error is less than 0.25%, the ADJUSTMENT ADDEND should be added to the MIN, TYP, and MAX specifications, where $K1 = 100 \cdot [(\text{SCF frequency} - 288 \text{ kHz}) / 288 \text{ kHz}]$. For errors greater than 0.25%, see Note 8.

§ All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 9: The filter gain outside of the passband is measured with respect to the gain at 1 kHz. The filter gain within the passband is measured with respect to the average gain within the passband. The passbands are 150 to 3600 Hz and 0 to 3600 Hz for the bandpass and low-pass filters respectively. For switched-capacitor filter clocks at frequencies other than 288 kHz, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 288 kHz.

serial port

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH} High-level output voltage	$I_{OH} = -300 \mu\text{A}$	2.4			V
V_{OL} Low-level output voltage	$I_{OL} = 2 \text{ mA}$			0.4	V
I_I Input current				±10	μA
C_i Input capacitance			15		pF
C_o Output capacitance			15		pF

† All typical values are at $T_A = 25^\circ\text{C}$.

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operating characteristics over recommended operating free-air temperature range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$, $V_{DD} = 5\text{ V}$

noise (measurement includes low-pass and bandpass switched-capacitor filters)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT	
Transmit noise	TLC32044C, E, I	With sin x/x correction			550	$\mu\text{V rms}$	
	TLC32044M				575	$\mu\text{V rms}$	
	TLC32045C, I				600	$\mu\text{V rms}$	
	TLC32044C, E, I	Without sin x/x correction	DX input = 00000000000000, constant input code		325	425	$\mu\text{V rms}$
	TLC32044M				325	450	$\mu\text{V rms}$
	TLC32045C, I					450	$\mu\text{V rms}$
	TLC32044C, E, I					18	dBrncO
TLC32045C, I				24	dBrncO		
Receive noise (see Note 10)	TLC32044C, E, I, M	Inputs grounded, gain = 1			300	500	$\mu\text{V rms}$
	TLC32045C, I					530	$\mu\text{V rms}$
	TLC32044C, E, I, M					18	dBrncO
	TLC32045C, I					24	dBrncO

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 10: The noise is computed by statistically evaluating the digital output of the A/D converter.

timing requirements

serial port recommended input signals

		MIN	MAX	UNIT
$t_c(\text{MCLK})$	Master clock cycle time	95		ns
	Master clock cycle time, TLC32044M	100	192	ns
$t_r(\text{MCLK})$	Master clock rise time		10	ns
$t_f(\text{MCLK})$	Master clock fall time		10	ns
	Master clock duty cycle	25%	75%	
	Master clock duty cycle, TLC32044M	42%	58%	
	$\overline{\text{RESET}}$ pulse duration (see Note 11)	800		ns
$t_{su}(\text{DX})$	DX setup time before SCLK \downarrow	20		ns
	DX setup time before SCLK \downarrow , TLC32044M	28		ns
$t_h(\text{DX})$	DX hold time after SCLK \downarrow		$t_c(\text{SCLK})/4$	ns

NOTE 11: $\overline{\text{RESET}}$ pulse duration is the amount of time that the reset pin is held below 0.8 V after the power supplies have reached their recommended values.



TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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serial port — AIC output signals

		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$	Shift clock (SCLK) cycle time		380			ns
$t_f(\text{SCLK})$	Shift clock (SCLK) fall time			50		ns
$t_r(\text{SCLK})$	Shift clock (SCLK) rise time			50		ns
	Shift clock (SCLK) duty cycle		45		55	%
$t_d(\text{CH-FL})$	Delay from SCLK↑ to FSR/FSX↓	$C_L = 50 \text{ pF}$			52	ns
$t_d(\text{CH-FH})$	Delay from SCLK↑ to FSR/FSX↑	$C_L = 50 \text{ pF}$			52	ns
$t_d(\text{CH-DR})$	DR valid after SCLK↑				90	ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to EODX/EODR↓ in word mode				90	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to EODX/EODR↑ in word mode				90	ns
$t_f(\text{EODX})$	EODX fall time			15		ns
$t_f(\text{EODR})$	EODR fall time			15		ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to EODX/EODR↓ in byte mode				100	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to EODX/EODR↑ in byte mode				100	ns
$t_d(\text{MH-SL})$	Delay from MSTR CLK↑ to SCLK↓			65		ns
$t_d(\text{MH-SH})$	Delay from MSTR CLK↑ to SCLK↑			65		ns

serial port — AIC output signals, TLC32044M

		MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$	Shift clock (SCLK) cycle time	400			ns
$t_f(\text{SCLK})$	Shift clock (SCLK) fall time		50		ns
$t_r(\text{SCLK})$	Shift clock (SCLK) rise time		50		ns
	Shift clock (SCLK) duty cycle		50		%
$t_d(\text{CH-FL})$	Delay from SCLK↑ to FSR/FSX↓			260	ns
$t_d(\text{CH-FH})$	Delay from SCLK↑ to FSR/FSX↑			260	ns
$t_d(\text{CH-DR})$	DR valid after SCLK↑			316	ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to EODX/EODR↓ in word mode			280	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to EODX/EODR↑ in word mode			280	ns
$t_f(\text{EODX})$	EODX fall time		15		ns
$t_f(\text{EODR})$	EODR fall time		15		ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to EODX/EODR↓ in byte mode		100		ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to EODX/EODR↑ in byte mode		100		ns
$t_d(\text{MH-SL})$	Delay from MSTR CLK↑ to SCLK↓		65		ns
$t_d(\text{MH-SH})$	Delay from MSTR CLK↑ to SCLK↑		65		ns

† Typical values are at $T_A = 25^\circ\text{C}$.

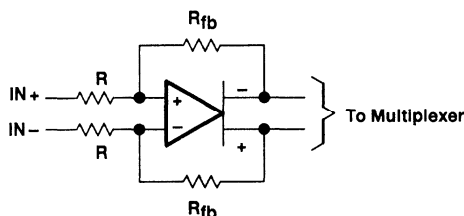
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Table 3. Gain Control Table (Analog Input Signal Required for Full-Scale A/D Conversion)

INPUT CONFIGURATIONS	CONTROL REGISTER BITS		ANALOG INPUT‡	A/D CONVERSION RESULT
	d6	d7		
Differential configuration Analog input = IN+ – IN– = AUX IN+ – AUX IN–	1	1	±6 V	Full-scale
	0	0		
	1	0	±3 V	Full-scale
	0	1	±1.5 V	Full-scale
Single-ended configuration Analog input = IN+ – ANLG GND = AUX IN+ – ANLG GND	1	1	±3 V	Half-scale
	0	0		
	1	0	±3 V	Full-scale
	0	1	±1.5 V	Full-scale

‡ In this example, V_{ref} is assumed to be 3 V. In order to minimize distortion, it is recommended that the analog input not exceed 0.1 dB below full scale.



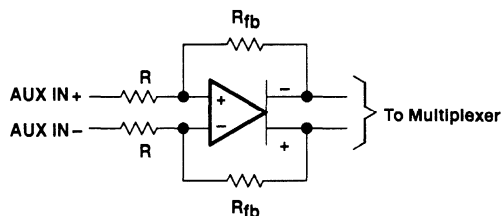
$$R_{fb} = R \text{ for } d6 = 1, d7 = 1$$

$$d6 = 0, d7 = 0$$

$$R_{fb} = 2R \text{ for } d6 = 1, d7 = 0$$

$$R_{fb} = 4R \text{ for } d6 = 0, d7 = 1$$

Figure 7. IN+ and IN– Gain Control Circuitry



$$R_{fb} = R \text{ for } d6 = 1, d7 = 1$$

$$d6 = 0, d7 = 0$$

$$R_{fb} = 2R \text{ for } d6 = 1, d7 = 0$$

$$R_{fb} = 4R \text{ for } d6 = 0, d7 = 1$$

Figure 8. AUX IN+ and AUX IN– Gain Control Circuitry

(sin x)/x correction

The AIC does not have (sin x)/x correction circuitry after the digital-to-analog converter. (Sin x)/x correction can be accomplished easily and efficiently in digital signal processor (DSP) software. Excellent correction accuracy can be achieved to a band edge of 3000 Hz by using a first-order digital correction filter. The results, which are shown in Table 4, are typical of the numerical correction accuracy that can be achieved for sample rates of interest. The filter requires only seven instruction cycles per sample on the TMS(SMJ)320 DSPs. With a 200-ns instruction cycle, nine instructions per sample represents an overhead factor of 1.4% and 1.7% for sampling rates of 8000 Hz and 9600 Hz, respectively. This correction adds a slight amount of group delay at the upper edge of the 300–3000-Hz band.

(sin x)/x roll-off for a zero-order hold function

The (sin x)/x roll-off for the AIC DAC zero-order hold function at a band-edge frequency of 3000 Hz for the various sampling rates is shown in the table below.

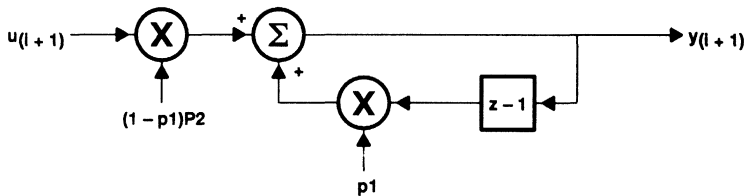
Table 4. (sin x)/x Roll-Off

f_s (Hz)	$20 \log \frac{\sin \pi f/f_s}{\pi f/f_s}$ ($f = 3000$ Hz) (dB)
7200	-2.64
8000	-2.11
9600	-1.44
14400	-0.63
19200	-0.35

The actual AIC (sin x)/x roll-off will be slightly less than the above figures because the AIC has less than a 100% duty cycle hold interval.

correction filter

To compensate for the (sin x)/x roll-off of the AIC, a first-order correction filter (shown below) is recommended.



The difference equation for this correction filter is:

$$y_i + 1 = p_2(1 - p_1)(u_{i+1}) + p_1 y_i$$

where the constant p_1 determines the pole locations.

The resulting squared magnitude transfer function is:

$$|H(f)|^2 = \frac{p_2^2 (1-p_1)^2}{1 - 2p_1 \cos(2 \pi f/f_s) + p_1^2}$$

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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correction results

Table 5 shows the optimum p values and the corresponding correction results for 8000-Hz and 9600-Hz sampling rates.

Table 5. Optimum P Values

f (Hz)	ERROR (dB)	ERROR (dB)
	$f_s = 8000$ Hz $p1 = -0.14813$ $p2 = 0.9888$	$f_s = 9600$ Hz $p1 = -0.1307$ $p2 = 0.9951$
300	-0.099	-0.043
600	-0.089	-0.043
900	-0.054	0
1200	-0.002	0
1500	0.041	0
1800	0.079	0.043
2100	0.100	0.043
2400	0.091	0.043
2700	-0.043	0
3000	-0.102	-0.043

TMS(SMJ)320 software requirements

The digital correction filter equation can be written in state variable form as follows:

$$Y = k1 \times Y + k2 \times U$$

Where

$$k1 = p1$$

$$k2 = (1 - p1) \times p2$$

Y = filter state

U = next I/O sample

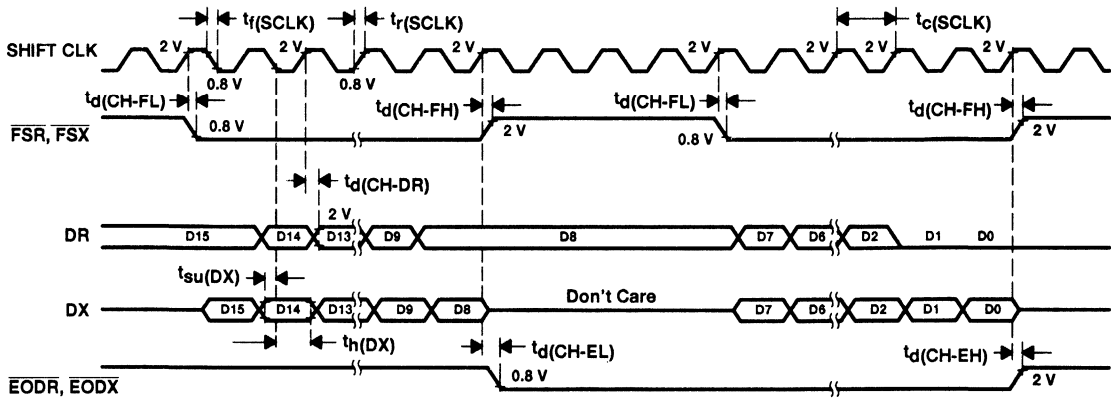
The coefficients k1 and k2 must be represented as 16-bit integers. The SACH instruction (with the proper shift) yields the correct result. With the assumption that the TMS(SMJ)320 processor page pointer and memory configuration are properly initialized, the equation can be executed in seven instructions or seven cycles with the following program:

```
ZAC
LT K2
MPY U
LTA K1
MPY Y
APAC
SACH (dma), (shift)
```

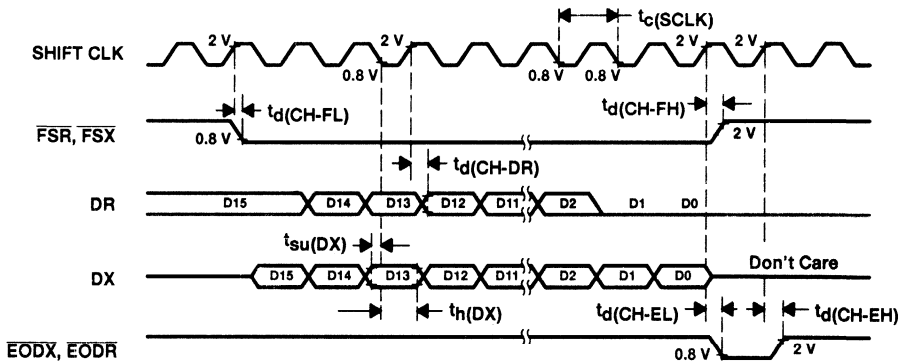
TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

SLAS017F - MARCH 1988 - REVISED MAY 1995

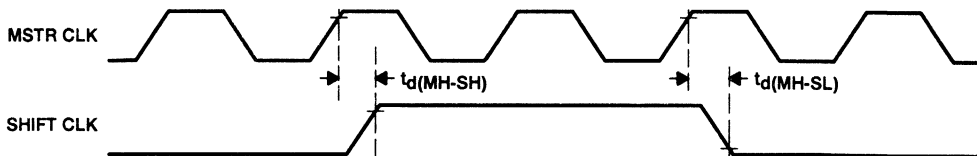
PARAMETER MEASUREMENT INFORMATION



(a) BYTE-MODE TIMING



(b) WORD-MODE TIMING



(c) SHIFT-CLOCK TIMING

Figure 9. Serial-Port Timing

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

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PARAMETER MEASUREMENT INFORMATION

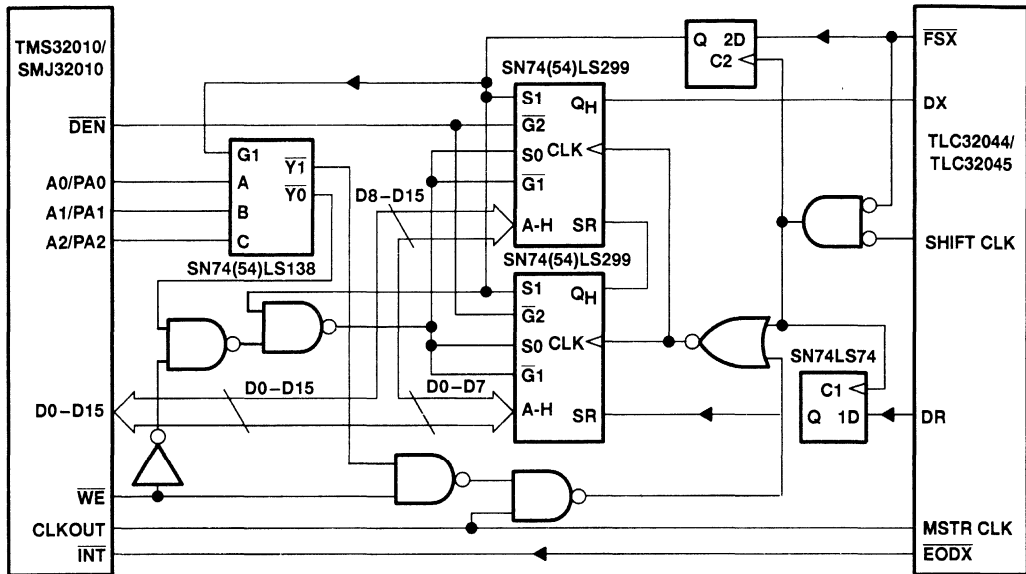


Figure 10. TMS(SMJ)32010/TMS(SMJ)320C15/(SMJ320E15)-TLC32044/45 Interface Circuit

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

SLAS017F – MARCH 1988 – REVISED MAY 1995

PARAMETER MEASUREMENT INFORMATION

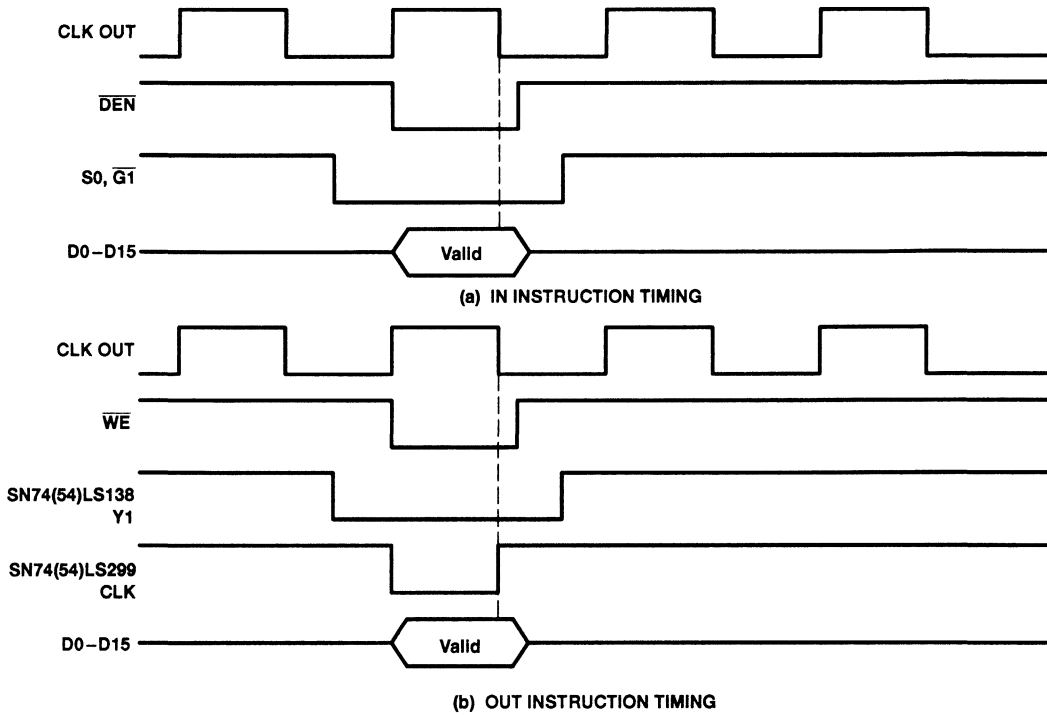


Figure 11. TMS(SMJ)32010/TMS(SMJ)320C15-TLC32044/TLC32045 Interface Timing

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I

VOICE-BAND ANALOG INTERFACE CIRCUITS

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TYPICAL CHARACTERISTICS

**AIC TRANSMIT AND RECEIVE
LOW-PASS FILTER**

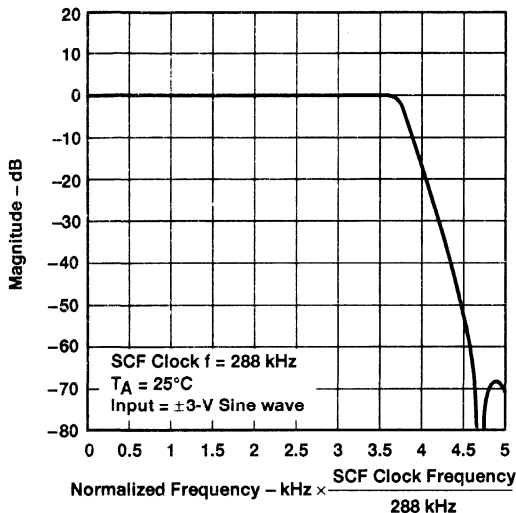


Figure 12

**AIC TRANSMIT AND RECEIVE
LOW-PASS FILTER**

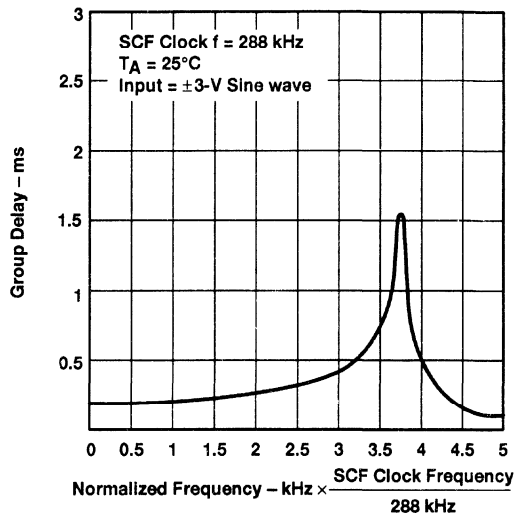


Figure 13

**AIC RECEIVE-CHANNEL
BANDPASS FILTER**

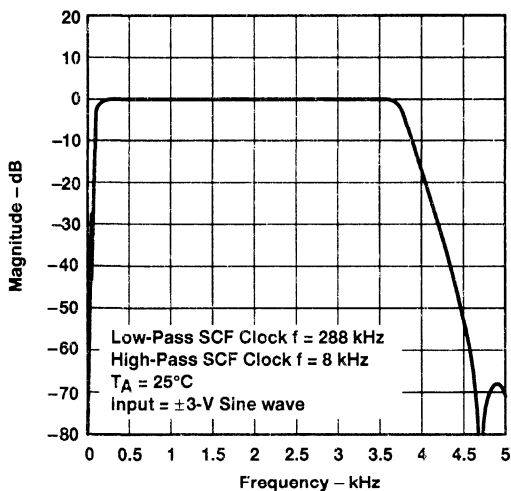


Figure 14

**AIC RECEIVE-CHANNEL
HIGH-PASS FILTER**

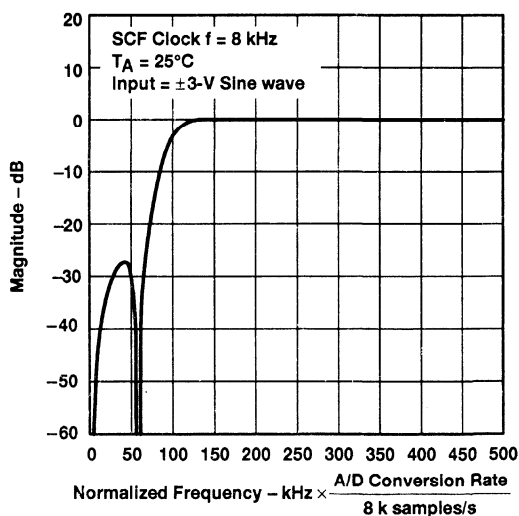


Figure 15

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I
VOICE-BAND ANALOG INTERFACE CIRCUITS

SLAS017F - MARCH 1988 - REVISED MAY 1995

TYPICAL CHARACTERISTICS

AIC RECEIVE CHANNEL
BANDPASS FILTER

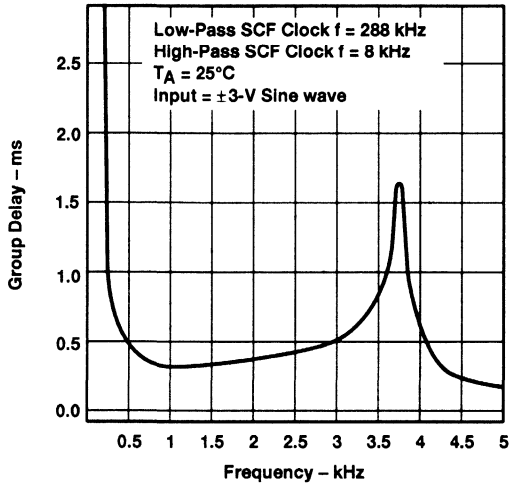


Figure 16

AIC (sin x)/x CORRECTION FILTER

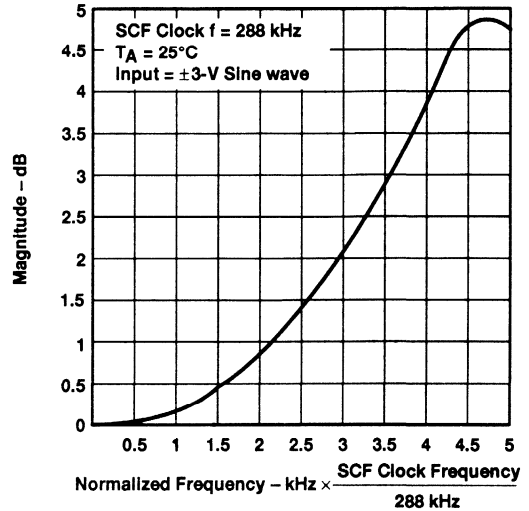


Figure 17

AIC (sin x)/x CORRECTION FILTER

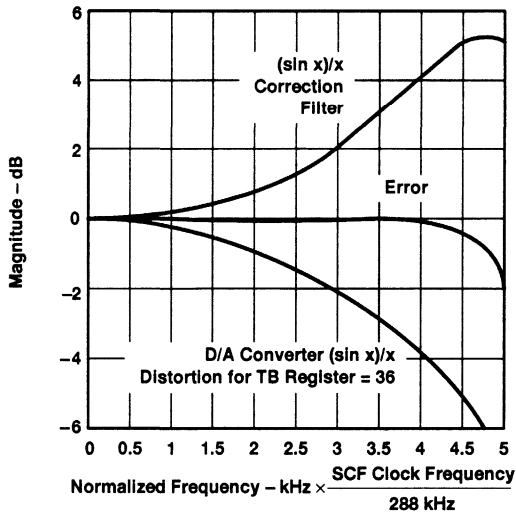


Figure 18

A/D SIGNAL-TO-DISTORTION RATIO
vs
INPUT-SIGNAL LEVEL

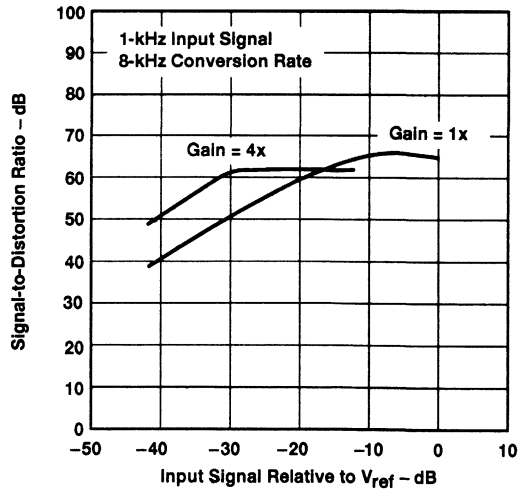


Figure 19

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

SLAS017F – MARCH 1988 – REVISED MAY 1995

TYPICAL CHARACTERISTICS

**A/D GAIN TRACKING
(GAIN RELATIVE TO GAIN
AT 0-dB INPUT-SIGNAL LEVEL)**

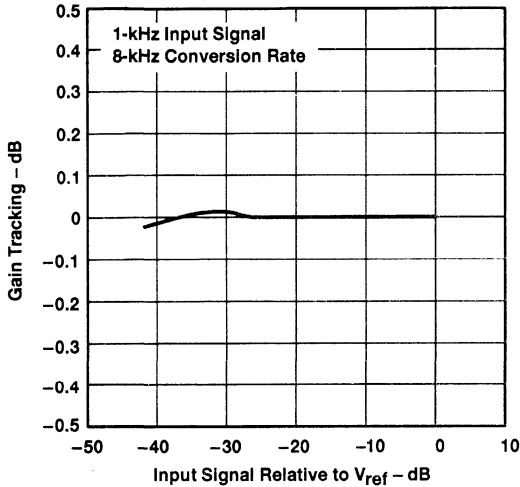


Figure 20

**D/A CONVERTER SIGNAL-TO-DISTORTION RATIO
VS
INPUT-SIGNAL LEVEL**

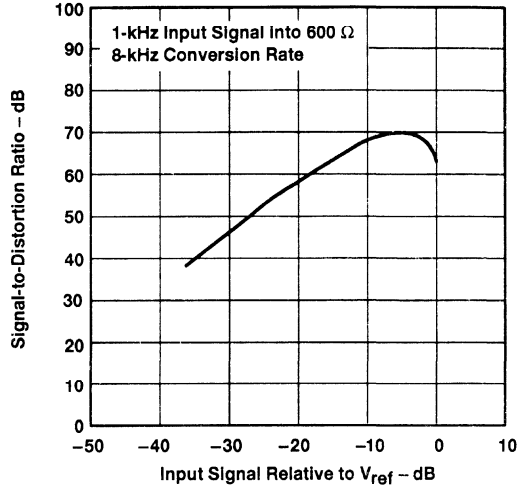


Figure 21

**D/A GAIN TRACKING
(GAIN RELATIVE TO GAIN
AT 0-dB INPUT-SIGNAL LEVEL)**

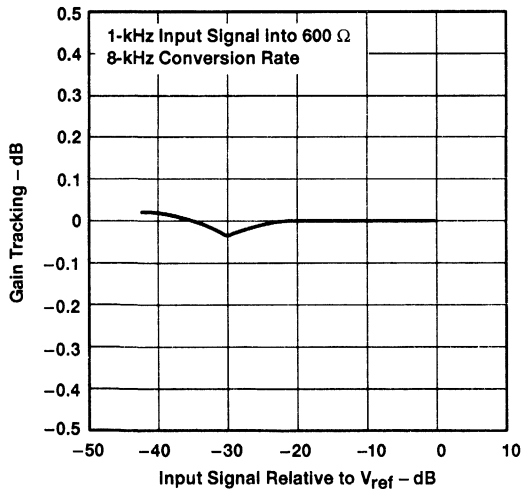


Figure 22

**A/D SECOND HARMONIC DISTORTION
VS
INPUT-SIGNAL LEVEL**

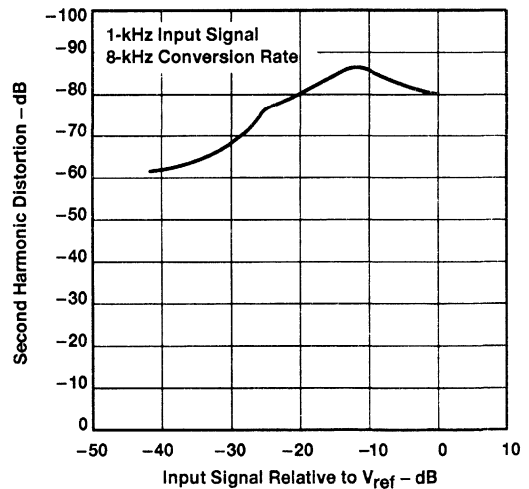


Figure 23

TYPICAL CHARACTERISTICS

D/A SECOND HARMONIC DISTORTION
 VS
 INPUT-SIGNAL LEVEL

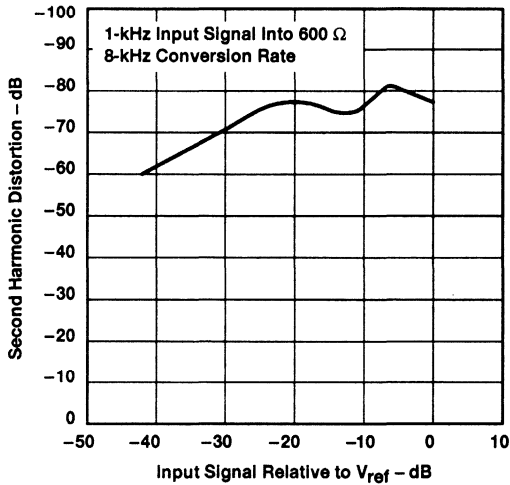


Figure 24

A/D THIRD HARMONIC DISTORTION
 VS
 INPUT-SIGNAL LEVEL

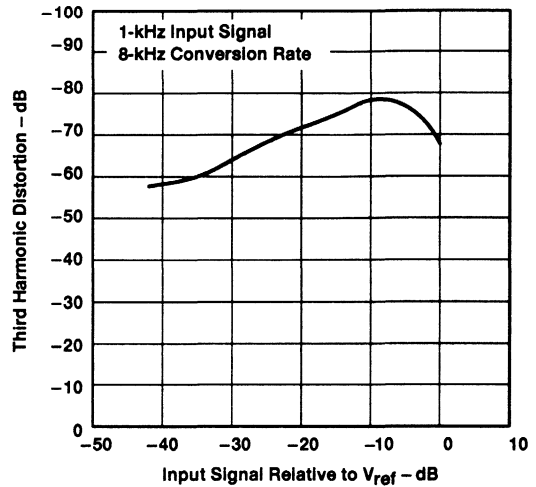


Figure 25

D/A THIRD HARMONIC DISTORTION
 VS
 INPUT-SIGNAL LEVEL

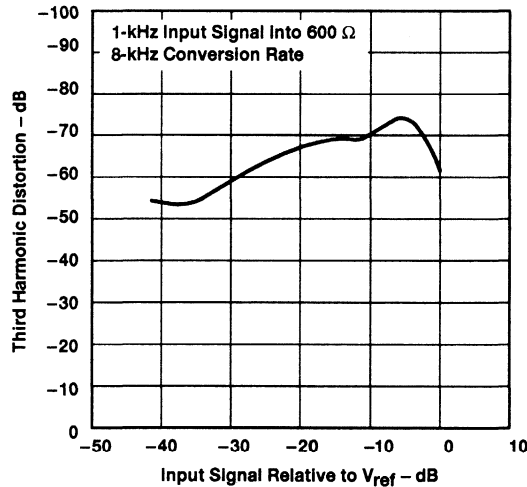


Figure 26

TLC32044C, TLC32044E, TLC32044I, TLC32044M, TLC32045C, TLC32045I VOICE-BAND ANALOG INTERFACE CIRCUITS

SLAS017F – MARCH 1988 – REVISED MAY 1995

APPLICATION INFORMATION

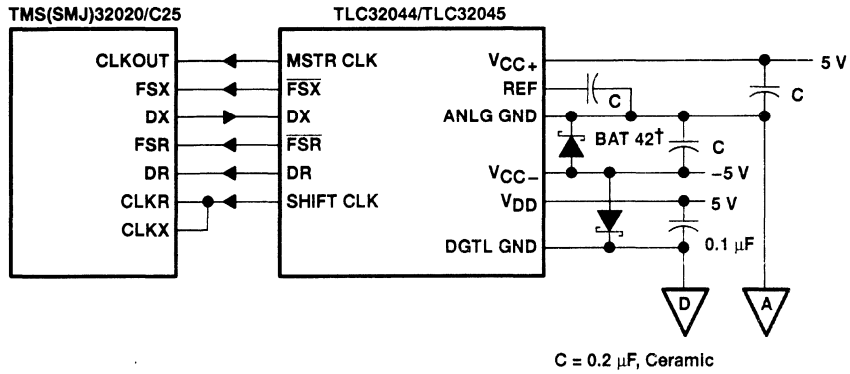


Figure 27. AIC Interface to the TMS(SMJ)32020/C25 Showing Decoupling Capacitors and Schottky Diode†

† Thomson Semiconductors

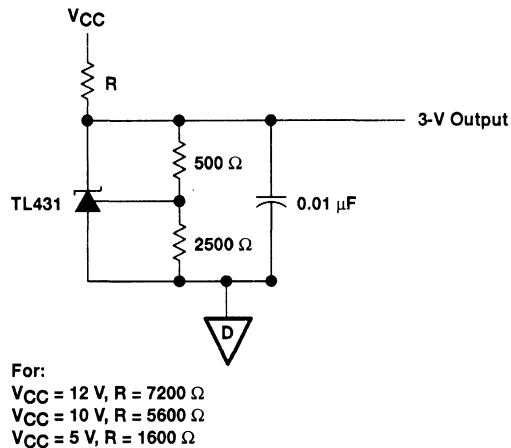


Figure 28. External Reference Circuit For TLC32044/TLC32045

TLC320AD56C SIGMA-DELTA ANALOG INTERFACE CIRCUIT

XLAS101 – MAY 1995

- CMOS Technology
- Single 5-V Power Supply Voltage or 5-V Analog and 3-V Digital Supply Voltages
- Power Dissipation:
 - Operating Mode . . . 150 mW Max
 - Power-Down Mode . . . 1 mW Max
- General Purpose 16-Bit Signal Processing
- 2s-Complement Data Format
- Dynamic Range . . . 91-dB Typ
- Total Signal-to-(Noise + Distortion):
 - ADC . . . 88-dB Min
 - DAC . . . 88-dB Min
- Differential Architecture
- Internal Reference Voltage (V_{ref})
- Internal 64× Oversampling
- Serial Port Interface
- Phone-Mode Output Control
- System-Test Mode, Digital-Loopback Test
- Supports All V.34 Sample Rates
- Supports Business-Audio Applications
- Variable Conversion Rate Selected As $MCLK/(F_k \times 256)$, $F_k = 1, 2, 3, \dots, 256$
- Master Clock Input Can Connect Directly To CLOCKOUT On TMS320C5x

description

The TLC320AD56C provides high resolution, low-speed signal conversion from digital-to-analog (D/A) and from analog-to-digital (A/D) using oversampling sigma-delta technology. This device consists of two serial-synchronous conversion paths (one for each data direction) and includes an interpolation filter before the DAC and a decimation filter after the ADC. Other overhead functions provide on-chip timing and control. The sigma-delta architecture produces high resolution analog-to-digital and digital-to-analog conversion at low system speeds and low cost.

The options and the circuit configurations of this device can be programmed through the serial interface. The options include reset, power-down, communications protocol, serial clock rate, signal sampling rate, and test mode. The TLC320AD56C is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

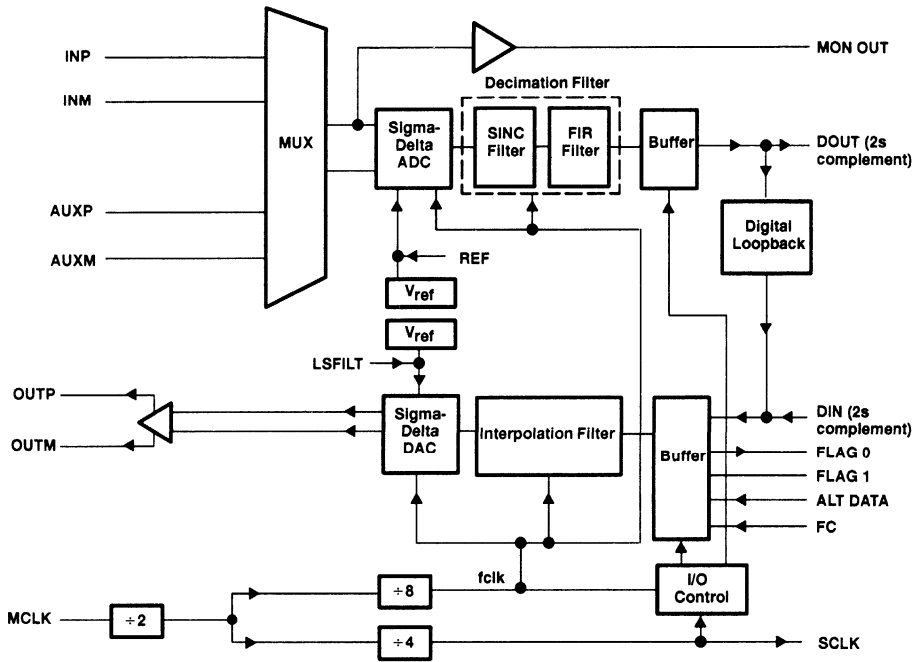
T _A	PACKAGE	
	PLASTIC CHIP CARRIER (FN)	QUAD FLATPACK (PTB)
0°C to 70°C	TLC320AD56CFN	TLC320AD56CPTB

PRODUCT PREVIEW

TLC320AD56C SIGMA-DELTA ANALOG INTERFACE CIRCUIT

XLAS101 – MAY 1995

functional block diagram



PRODUCT PREVIEW



TLC320AD65C 16-BIT SIGMA-DELTA STEREO CODEC

XLAS099 – MAY 1995

- Single 5-V Power Supply
- Stereo 16-Bit Sigma-Delta Audio Converter
- General Purpose 16-Bit Signal Processing
- Sample Rates from 4 kHz to 48 kHz
- High Current Capacity Output Drivers For Driving Line Outputs or 32 Ω Stereo Headphones
- On-Chip Support Real Time Data Compression/Decompression For A-Law, μ -Law, and Adaptive Differential Pulse Code Modulation-International Multimedia Association (ADPCM-IMA)
- Differential Architecture
- Register Compatible Functional Upgrade From AD1848, CS4248, and CS4231
- Stereo Microphone Preamplifier—Uniquely Mixable in Capture A/D Path
- Fully Independent Analog Input Capture and Playback Mixing Capability
- Mono Channel Input
- Mono Speaker Driver With 32 Ω Drive Capability
- Internal Reference Voltage (V_{ref})
- Supports Little and Big Endian Formats
- Byte Wide Parallel Port Interface For ISA, EISA Bus Support
- Full Duplex Transfers With Host PC Using On-Chip Dual DMA Count Registers
- 8-Bit DMA Data Transfers With Host Utilizing On-Chip Dual 64 Byte FIFOs With Independent Capture and Playback Programmable Interrupt Flag Depth

description

The TLC320AD65C sigma-delta technology audio stereo codec provides 16-bit audio for computer multimedia applications.

The TLC320AD65C provides upgraded functionality, flexibility, and performance from the 16-bit AD1848, CS4248, and the CS4231. Flexible analog mixing for both record and playback paths, provide capability for either the normal ADC with DAC playback paths or an all analog input to output mixing path without any digital conversions. This device consists of four synchronous conversion paths. Four stereo inputs and one mono input are provided. The stereo line outputs are capable of driving 32- Ω stereo headphones. The mono channel output driver is capable of driving a 32- Ω speaker. Gain and mixing control and sample rate selections are provided for maximum flexibility. Additional functions provide digital filtering and on-chip timing and control. The TLC320AD65C is characterized for operation from 0°C to 70°C.

AVAILABLE OPTIONS

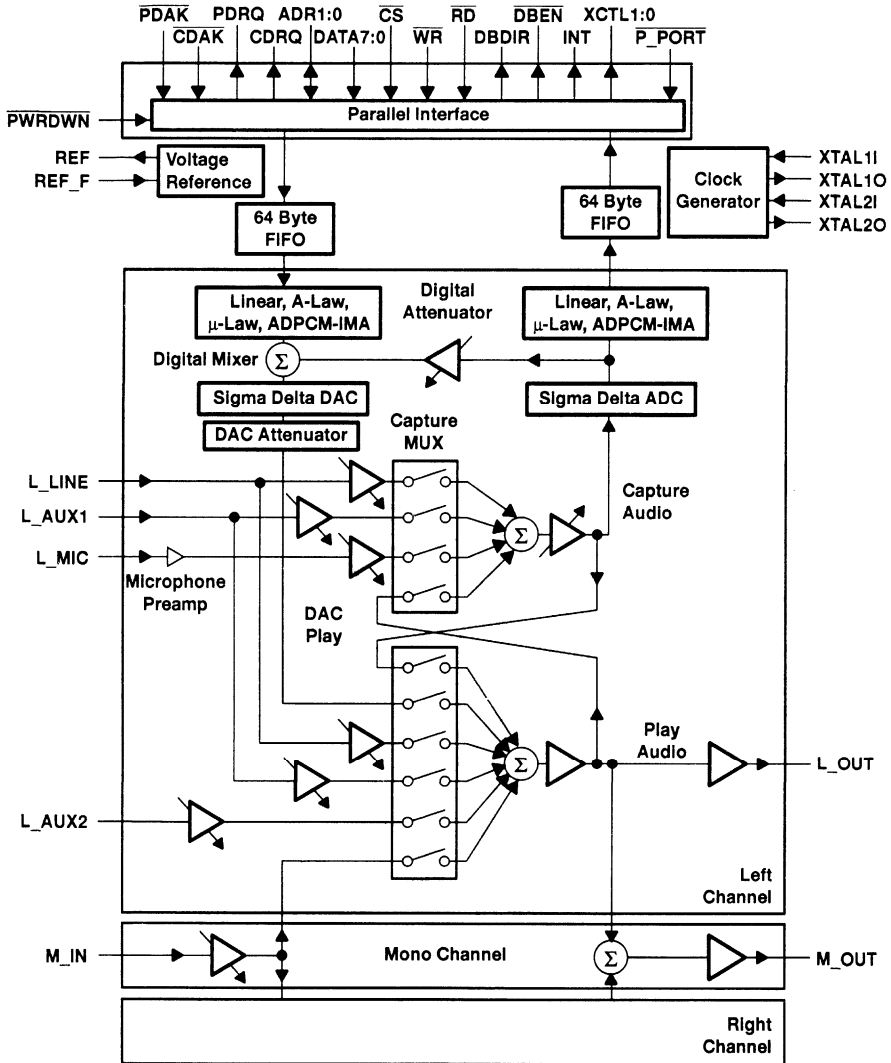
T _A	PACKAGE	
	PLASTIC CHIP CARRIER (FN)	QUAD FLATPACK (PZ)
0°C to 70°C	TLC320AD65CFN	TLC320AD65CPZ

PRODUCT PREVIEW

TLC320AD65C 16-BIT SIGMA-DELTA STEREO CODEC

XLAS099 – MAY 1995

functional block diagram



PRODUCT PREVIEW



General Information	1
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Video Interface Palettes	6
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Mechanical Data	9
Appendix	A

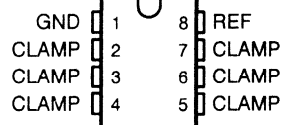
↳ Special Functions

TL7726C, TL7726I, TL7726Q HEX CLAMPING CIRCUITS

SLAS078 – D4102, SEPTEMBER 1993

- Protects Against Latch-Up
- 25-mA Current Sink in Active State
- Less Than 1-mW Dissipation in Standby Condition
- Ideal for Applications in Environments Where Large Transient Spikes Occur
- Stable Operation for All Values of Capacitive Load
- No Output Overshoot

D OR P PACKAGE
(TOP VIEW)



description

The TL7726C, TL7726I, and TL7726Q each consist of six identical clamping circuits that monitor an input voltage with respect to a reference value, REF. For an input voltage (V_I) in the range of GND to $< REF$, the clamping circuits present a very high impedance to ground, drawing current of less than 10 μA . The clamping circuits are active for $V_I < GND$ or $V_I > REF$ when they have a very low impedance and can sink up to 25 mA.

These characteristics make the TL7726C, TL7726I, and TL7726Q ideal as protection devices for CMOS semiconductor devices in environments where there are large positive or negative transients to protect analog-to-digital converters in automotive or industrial systems. The use of clamping circuits provides a safeguard against potential latch-up.

The TL7726C is characterized for operation over the temperature range of 0°C to 70°C. The TL7726I is characterized for operation over the temperature range of -25°C to 85°C. The TL7726Q is characterized for operation over the temperature range of -40°C to 125°C.

AVAILABLE OPTIONS

OPERATING TEMPERATURE RANGE	DEVICE	PACKAGE
0°C – 70°C	TL7726CD	8-pin SO
0°C – 70°C	TL7726CP	8-pin DIP
-25°C – 85°C	TL7726ID	8-pin SO
-25°C – 85°C	TL7726IP	8-pin DIP
-40°C – 125°C	TL7726QD	8-pin SO
-40°C – 125°C	TL7726QP	8-pin DIP

TL7726C, TL7726I, TL7726Q HEX CLAMPING CIRCUITS

SLAS078 – D4102, SEPTEMBER 1993

absolute maximum ratings over operating free-air temperature (unless otherwise noted)

Reference voltage, V_{ref}	6 V
Clamping current, I_{IK}	± 50 mA
Junction temperature, T_J	150°C
Continuous total dissipation	See Dissipation Rating Table
Operating free-air temperature range, T_A : TL7726C	0°C to 70°C
TL7726I	-40°C to 85°C
TL7726Q	-40°C to 125°C
Storage temperature range	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

DISSIPATION RATING TABLE

PACKAGE	$T_A \leq 25^\circ\text{C}$ POWER RATING	DERATING FACTOR ABOVE $T_A \leq 25^\circ\text{C}$	$T_A = 70^\circ\text{C}$ POWER RATING	$T_A = 85^\circ\text{C}$ POWER RATING	$T_A = 125^\circ\text{C}$ POWER RATING
D	728 mW	5.8 mW/°C	460 mW	374 mW	144 mW
P	924 mW	9.5 mW/°C	757 mW	615 mW	237 mW

recommended operating conditions

	MIN	MAX	UNIT
Reference voltage, V_{ref}	4.5	5.5	V
Input clamping current, I_{IK}	$V_I \geq V_{ref}$	25	mA
	$V_I \leq \text{GND}$	-25	

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{IK+} Positive clamp voltage	$I_I = 20$ mA	V_{ref}		$V_{ref} + 200$	mV
V_{IK-} Negative clamp voltage	$I_I = 20$ mA	-200		0	mV
I_Z Reference current	$V_{ref} = 5$ V		25	60	μA
I_I Input current	$V_{ref} - 50$ mV $\leq V_I \leq V_{ref}$			10	μA
	$\text{GND} \leq V_I \leq 50$ mV	-10			μA
	50 mV $\leq V_I \leq V_{ref} - 50$ mV	-1		1	μA

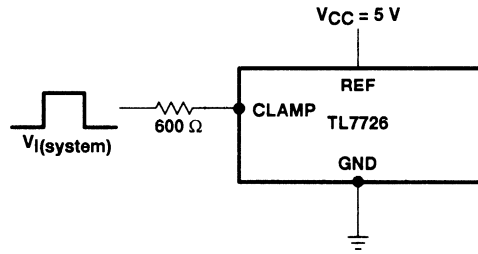
† All typical values are at $T_A = 25^\circ\text{C}$.

switching characteristics specified at $T_A = 25^\circ\text{C}$

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
t_s Settling time	$V_I(\text{system}) = \pm 13$ V, $R_I = 600$ Ω , Measured at 10% to 90%, See Figure 1		30	μs



PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

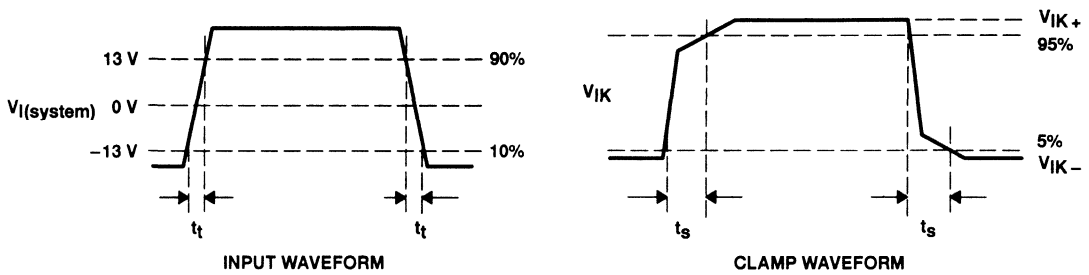


Figure 1. Switching Characteristics

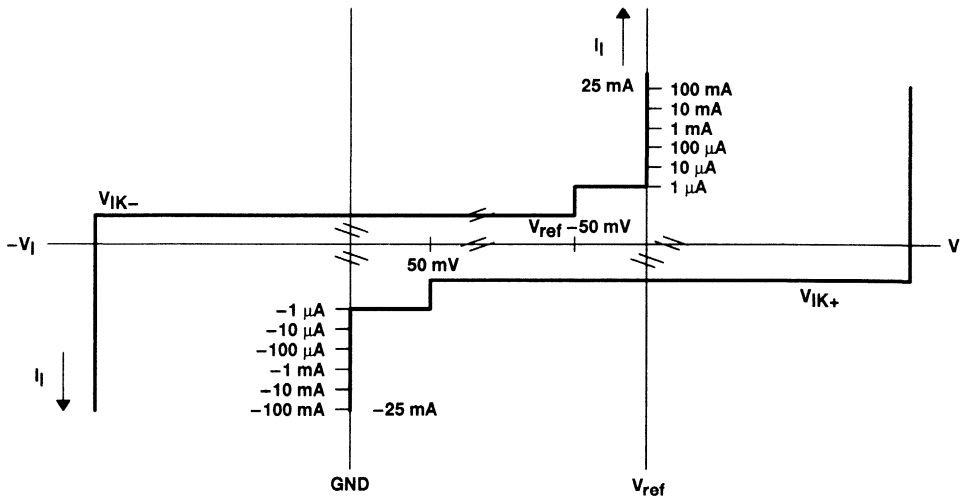
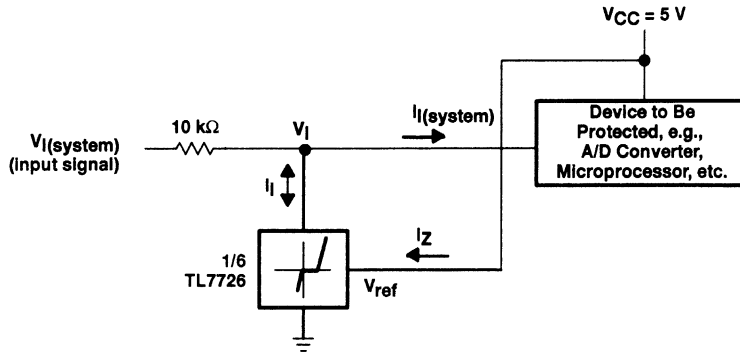


Figure 2. Tolerance Band for Clamping Circuit

TL7726C, TL7726I, TL7726Q HEX CLAMPING CIRCUITS

SLAS078 – D4102, SEPTEMBER 1993

APPLICATION INFORMATION



Example: If $I_I \gg I_{I(\text{system})}$, i.e., $V_I(\text{system}) > V_{\text{ref}} + 200 \text{ mV}$
where:

$I_{I(\text{system})}$ = Input current to the device being protected
 $V_I(\text{system})$ = Input voltage to the device being protected
then the maximum input voltage

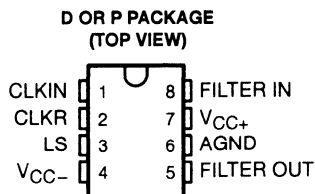
$$\begin{aligned} V_{I(\text{system})\text{max}} &= V_{\text{ref}} + I_{I\text{max}}(10\text{k}\Omega) \\ &= 5 \text{ V} + 25 \text{ mA}(10\text{k}\Omega) \\ &= 5 \text{ V} + 250 \text{ V} \\ &= 255 \text{ V} \end{aligned}$$

Figure 3. Typical Application

TLC04/MF4A-50, TLC14/MF4A-100 BUTTERWORTH FOURTH-ORDER LOW-PASS SWITCHED-CAPACITOR FILTERS

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- Low Clock-to-Cutoff-Frequency Ratio Error
TLC04/MF4A-50 . . . $\pm 0.8\%$
TLC14/MF4A-100 . . . $\pm 1\%$
- Filter Cutoff Frequency Dependent Only on External-Clock Frequency Stability
- Minimum Filter Response Deviation Due to External Component Variations Over Time and Temperature
- Cutoff Frequency Range From 0.1 Hz to 30 kHz, $V_{CC\pm} = \pm 2.5\text{ V}$
- 5-V to 12-V Operation
- Self Clocking or TTL-Compatible and CMOS-Compatible Clock Inputs
- Low Supply-Voltage Sensitivity
- Designed to be Interchangeable With National MF4-50 and MF4-100



description

The TLC04/MF4A-50 and TLC14/MF4A-100 are monolithic Butterworth low-pass switched-capacitor filters. Each is designed as a low-cost, easy-to-use device providing accurate fourth-order low-pass filter functions in circuit design configurations.

Each filter features cutoff frequency stability that is dependent only on the external-clock frequency stability. The cutoff frequency is clock tunable and has a clock-to-cutoff frequency ratio of 50:1 with less than $\pm 0.8\%$ error for the TLC04/MF4A-50 and a clock-to-cutoff frequency ratio of 100:1 with less than $\pm 1\%$ error for the TLC14/MF4A-100. The input clock features self-clocking or TTL- or CMOS-compatible options in conjunction with the level shift (LS) terminal.

The TLC04C/MF4A-50C and TLC14C/MF4A-100C are characterized for operation from 0°C to 70°C . The TLC04I/MF4A-50I and TLC14I/MF4A-100I are characterized for operation from -40°C to 85°C . The TLC04M/MF4A-50M and TLC14M/MF4A-100M are characterized over the full military temperature range of -55°C to 125°C .

AVAILABLE OPTIONS

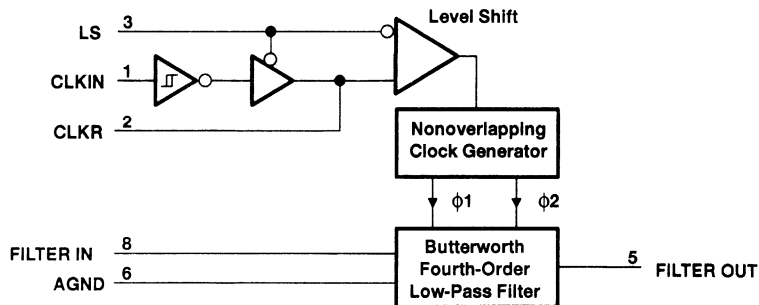
T _A	CLOCK-TO-CUTOFF FREQUENCY RATIO	PACKAGE	
		SMALL OUTLINE (D)	PLASTIC DIP (P)
0°C to 70°C	50:1	TLC04CD/MF4A-50CD	TLC04CP/MF4A-50CP
	100:1	TLC14CD/MF4A-100CD	TLC14CP/MF4A-100CP
-40°C to 85°C	50:1	TLC04ID/MF4A-50ID	TLC04IP/MF4A-50IP
	100:1	TLC14ID/MF4A-100ID	TLC14IP/MF4A-100IP
-55°C to 125°C	50:1		TLC04MP/MF4A-50MP
	100:1		TLC14MP/MF4A-100MP

The D package is available taped and reeled. Add the suffix R to the device type (e.g., TLC04CDR/MF4A-50CDR).

TLC04/MF4A-50, TLC14/MF4A-100 BUTTERWORTH FOURTH-ORDER LOW-PASS SWITCHED-CAPACITOR FILTERS

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functional block diagram



Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AGND	6	I	Analog ground. The noninverting input to the operational amplifiers of the Butterworth fourth-order low-pass filter.
CLKIN	1	I	Clock in. CLKIN is the clock input terminal for CMOS-compatible clock or self-clocking options. For either option, LS is at V_{CC-} . For self-clocking, a resistor is connected between CLKIN and CLKR and a capacitor is connected from CLKIN to ground.
CLKR	2	I	Clock R. CLKR is the clock input for a TTL-compatible clock. For a TTL clock, LS is connected to midsupply and CLKIN can be left open, but it is recommended that it be connected to either V_{CC+} or V_{CC-} .
FILTER IN	8	I	Filter input
FILTER OUT	5	O	Butterworth fourth-order low-pass filter output
LS	3	I	Level shift. LS accommodates the various input clocking options. For CMOS-compatible clocks or self-clocking, LS is at V_{CC-} and for TTL-compatible clocks, LS is at midsupply.
V_{CC+}	7	I	Positive supply voltage terminal
V_{CC-}	4	I	Negative supply voltage terminal

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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, $V_{CC\pm}$ (see Note 1)	± 7 V
Operating free-air temperature range, T_A :	TLC04C/MF4A-50C, TLC14C/MF4A-100C 0°C to 70°C
	TLC04I/MF4A-50I, TLC14I/MF4A-100I -40°C to 85°C
	TLC04M/MF4A-50M, TLC14M/MF4A-100M	.. -55°C to 125°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to the AGND terminal.

recommended operating conditions

		TLC04/MF4A-50		TLC14/MF4A-100		UNIT
		MIN	MAX	MIN	MAX	
Positive supply voltage, V_{CC+}		2.25	6	2.25	6	V
Negative supply voltage, V_{CC-}		-2.25	-6	-2.25	-6	V
High-level input voltage, V_{IH}		2		2		V
Low-level input voltage, V_{IL}		0.8		0.8		V
Clock frequency, f_{clock} (see Note 2)	$V_{CC\pm} = \pm 2.5$ V	5	1.5×10^6	5	1.5×10^6	Hz
	$V_{CC\pm} = \pm 5$ V	5	2×10^6	5	2×10^6	
Cutoff frequency, f_{CO} (see Note 3)		0.1	40×10^3	0.05	20×10^3	Hz
Operating free-air temperature, T_A	TLC04C/MF4A-50C, TLC14C/MF4A-100C	0	70	0	70	°C
	TLC04I/MF4A-50I, TLC14I/MF4A-100I	-40	85	-40	85	
	TLC04M/MF4A-50M, TLC14M/MF4A-100M	-55	125	-55	125	

NOTES: 2. Above 250 kHz, the input clock duty cycle should be 50% to allow the operational amplifiers the maximum time to settle while processing analog samples.

3. The cutoff frequency is defined as the frequency where the response is 3.01 dB less than the dc gain of the filter.

electrical characteristics over recommended operating free-air temperature range, $V_{CC+} = 2.5$ V, $V_{CC-} = -2.5$ V, $f_{clock} \leq 250$ kHz (unless otherwise noted)

filter section

PARAMETER		TEST CONDITIONS	TLC04/MF4A-50		TLC14/MF4A-100		UNIT	
			MIN	TYP‡	MAX	MIN		TYP‡
V_{OO}	Output offset voltage		25		50		mV	
V_{OM}	Peak output voltage	$R_L = 10$ k Ω	V_{OM+}	1.8	2	1.8	2	V
			V_{OM-}	-1.25	-1.7	-1.25	-1.7	
I_{OS}	Short-circuit output current	$T_A = 25^\circ\text{C}$, See Note 4	Source	-0.5		-0.5		mA
			Sink	4		4		
I_{CC}	Supply current	$f_{clock} = 250$ kHz	1.2	2.25	1.2	2.25	mA	

‡ All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: $I_{OS}(\text{source})$ is measured by forcing the output to its maximum positive voltage and then shorting the output to the V_{CC-} terminal. $I_{OS}(\text{sink})$ is measured by forcing the output to its maximum negative voltage and then shorting the output to the V_{CC+} terminal.

TLC04/MF4A-50, TLC14/MF4A-100 BUTTERWORTH FOURTH-ORDER LOW-PASS SWITCHED-CAPACITOR FILTERS

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electrical characteristics over recommended operating free-air temperature range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$, $f_{\text{clock}} \leq 250\text{ kHz}$ (unless otherwise noted)

filter section

PARAMETER		TEST CONDITIONS	TLC04/MF4A-50			TLC14/MF4A-100			UNIT
			MIN	TYP†	MAX	MIN	TYP†	MAX	
V_{OO}	Output offset voltage		150			200			mV
V_{OM}	Peak output voltage	$R_L = 10\text{ k}\Omega$	V_{OM+}	3.75	4.3	3.75	4.5	V	
			V_{OM-}	-3.75	-4.1	-3.75	-4.1		
I_{OS}	Short-circuit output current	$T_A = 25^\circ\text{C}$, See Note 4	Source	-2			-2	mA	
			Sink	5			5		
I_{CC}	Supply current	$f_{\text{clock}} = 250\text{ kHz}$	1.8	3	1.8	3	mA		
k_{SVS}	Supply voltage sensitivity (see Figures 1 and 2)		-30			-30			dB

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 4: $I_{OS(\text{source})}$ is measured by forcing the output to its maximum positive voltage and then shorting the output to the V_{CC-} terminal. $I_{OS(\text{sink})}$ is measured by forcing the output to its maximum negative voltage and then shorting the output to the V_{CC+} terminal.

clocking section

PARAMETER		TEST CONDITIONS		MIN	TYP†	MAX	UNIT
V_{IT+}	Positive-going input threshold voltage	CLKIN	$V_{CC+} = 10\text{ V}$, $V_{CC-} = 0$	6.1	7	8.9	V
			$V_{CC+} = 5\text{ V}$, $V_{CC-} = 0$	3.1	3.5	4.4	
V_{IT-}	Negative-going input threshold voltage	CLKIN	$V_{CC+} = 10\text{ V}$, $V_{CC-} = 0$	1.3	3	3.8	V
			$V_{CC+} = 5\text{ V}$, $V_{CC-} = 0$	0.6	1.5	1.9	
V_{hys}	Hysteresis voltage ($V_{IT+} - V_{IT-}$)	CLKIN	$V_{CC+} = 10\text{ V}$, $V_{CC-} = 0$	2.3	4	7.6	V
			$V_{CC+} = 5\text{ V}$, $V_{CC-} = 0$	1.2	2	3.8	
V_{OH}	High-level output voltage	CLKR	$V_{CC} = 10\text{ V}$	9			V
			$V_{CC} = 5\text{ V}$	4.5			
V_{OL}	Low-level output voltage	CLKR	$V_{CC} = 10\text{ V}$	1			V
			$V_{CC} = 5\text{ V}$	0.5			
Input leakage current		CLKR	$V_{CC} = 10\text{ V}$	2			μA
			$V_{CC} = 5\text{ V}$	2			
I_O	Output current	CLKR	$V_{CC} = 10\text{ V}$	-3			mA
			$V_{CC} = 5\text{ V}$	-0.75			
			$V_{CC} = 10\text{ V}$	3			mA
			$V_{CC} = 5\text{ V}$	0.75			

† All typical values are at $T_A = 25^\circ\text{C}$.

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operating characteristics over recommended operating free-air temperature range, $V_{CC+} = 2.5\text{ V}$, $V_{CC-} = -2.5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC04/MF4A-50			TLC14/MF4A-100			UNIT	
		MIN	TYP†	MAX	MIN	TYP†	MAX		
Maximum clock frequency, f_{max}	See Note 2	1.5	3		1.5	3		MHz	
Clock-to-cutoff-frequency ratio (f_{clock}/f_{co})	$f_{clock} \leq 250\text{ kHz}$, $T_A = 25^\circ\text{C}$	49.27	50.07	50.87	99	100	101	Hz/Hz	
Temperature coefficient of clock-to-cutoff frequency ratio	$f_{clock} \leq 250\text{ kHz}$	±25			±25			ppm/°C	
Frequency response above and below cutoff frequency (see Note 5)	$f_{co} = 5\text{ kHz}$, $f_{clock} = 250\text{ kHz}$, $T_A = 25^\circ\text{C}$	$f = 6\text{ kHz}$	-7.9	-7.57	-7.1			dB	
		$f = 4.5\text{ kHz}$	-1.7	-1.46	-1.3				
	$f_{co} = 5\text{ kHz}$, $f_{clock} = 250\text{ kHz}$, $T_A = 25^\circ\text{C}$	$f = 3\text{ kHz}$				-7.9	-7.42	-7.1	dB
		$f = 2.25\text{ kHz}$				-1.7	-1.51	-1.3	
Dynamic range (see Note 6)	$T_A = 25^\circ\text{C}$	80			78			dB	
Stop-band frequency attenuation at $2f_{co}$	$f_{clock} \leq 250\text{ kHz}$	24	25		24	25		dB	
Voltage amplification, dc	$f_{clock} \leq 250\text{ kHz}$, $R_S \leq 2\text{ k}\Omega$	-0.15	0	0.15	-0.15	0	0.15	dB	
Peak-to-peak clock feedthrough voltage	$T_A = 25^\circ\text{C}$	5			5			mV	

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTES: 2. Above 250 kHz, the input clock duty cycle should be 50% to allow the operational amplifiers the maximum time to settle while processing analog samples.

5. The frequency responses at f are referenced to a dc gain of 0 dB.

6. The dynamic range is referenced to 1.06 V rms (1.5 V peak) where the wideband noise over a 30-kHz bandwidth is typically 106 μV rms for the TLC04/MF4A-50 and 135 μV rms for the TLC14/MF4A-100.

operating characteristics over recommended operating free-air temperature range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TLC04/MF4A-50			TLC14/MF4A-100			UNIT	
		MIN	TYP†	MAX	MIN	TYP†	MAX		
Maximum clock frequency, f_{max}	See Note 2	2	4		2	4		MHz	
Clock-to-cutoff-frequency ratio (f_{clock}/f_{co})	$f_{clock} \leq 250\text{ kHz}$, $T_A = 25^\circ\text{C}$	49.58	49.98	50.38	99	100	101	Hz/Hz	
Temperature coefficient of clock-to-cutoff frequency ratio	$f_{clock} \leq 250\text{ kHz}$	±15			±15			ppm/°C	
Frequency response above and below cutoff frequency (see Note 5)	$f_{co} = 5\text{ kHz}$, $f_{clock} = 250\text{ kHz}$, $T_A = 25^\circ\text{C}$	$f = 6\text{ kHz}$	-7.9	-7.57	-7.1			dB	
		$f = 4.5\text{ kHz}$	-1.7	-1.44	-1.3				
	$f_{co} = 5\text{ kHz}$, $f_{clock} = 250\text{ kHz}$, $T_A = 25^\circ\text{C}$	$f = 3\text{ kHz}$				-7.9	-7.42	-7.1	dB
		$f = 2.25\text{ kHz}$				-1.7	-1.51	-1.3	
Dynamic range (see Note 6)	$T_A = 25^\circ\text{C}$	86			84			dB	
Stop-band frequency attenuation at $2f_{co}$	$f_{clock} \leq 250\text{ kHz}$	24	25		24	25		dB	
Voltage amplification, dc	$f_{clock} \leq 250\text{ kHz}$, $R_S \leq 2\text{ k}\Omega$	-0.15	0	0.15	-0.15	0	0.15	dB	
Peak-to-peak clock feedthrough voltage	$T_A = 25^\circ\text{C}$	7			7			mV	

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTES: 2. Above 250 kHz, the input clock duty cycle should be 50% to allow the operational amplifiers the maximum time to settle while processing analog samples.

5. The frequency responses at f are referenced to a dc gain of 0 dB.

6. The dynamic range is referenced to 2.82 V rms (4 V peak) where the wideband noise over a 30-kHz bandwidth is typically 142 μV rms for the TLC04/MF4A-50 and 178 μV rms for the TLC14/MF4A-100.

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TYPICAL CHARACTERISTICS

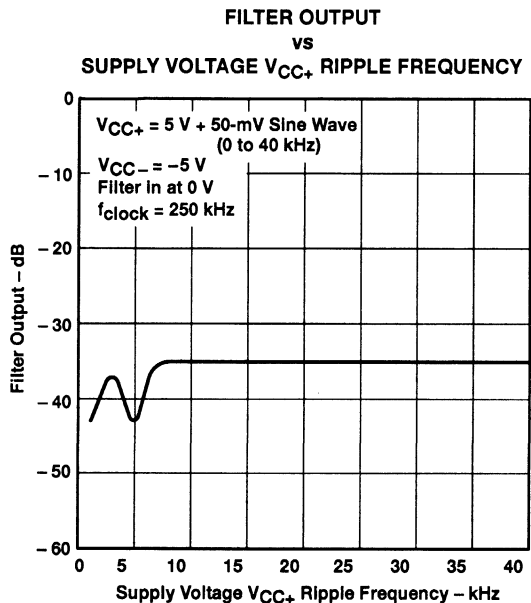


Figure 1

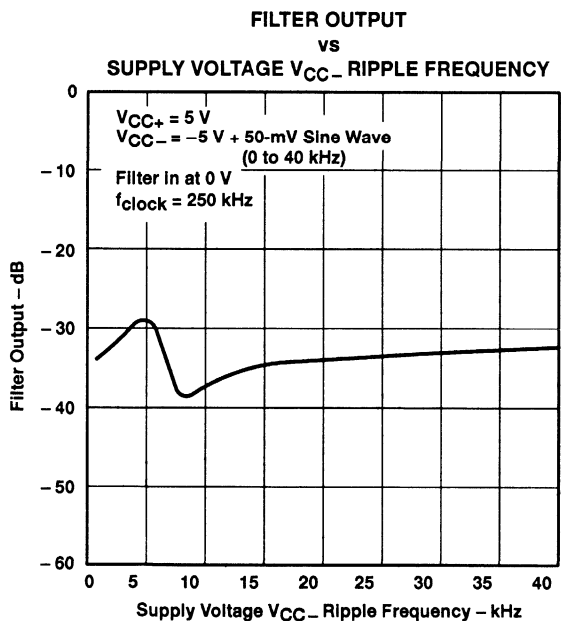


Figure 2



APPLICATION INFORMATION

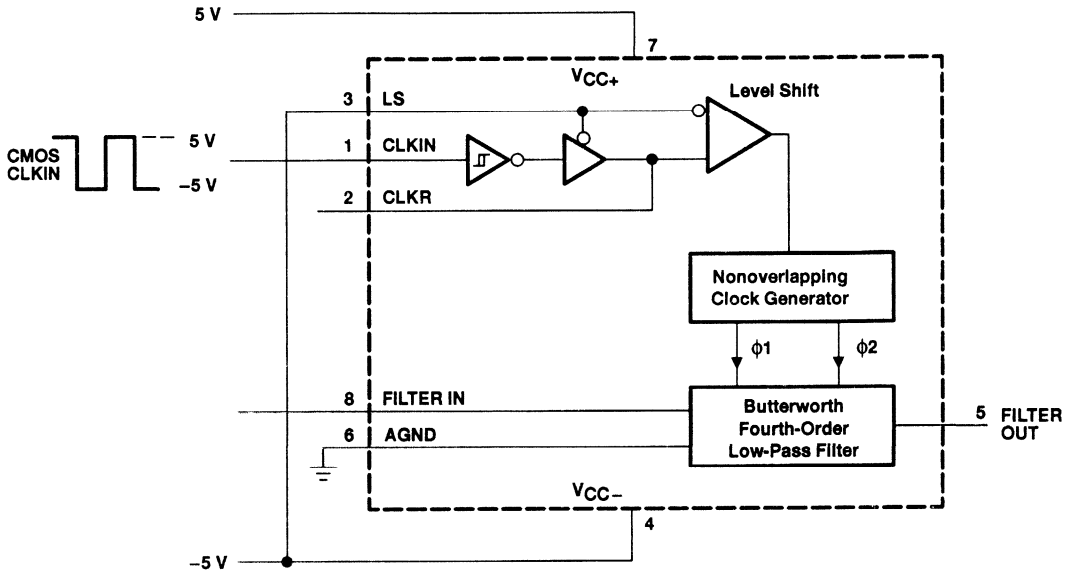


Figure 3. CMOS-Clock-Driven Dual-Supply Operation

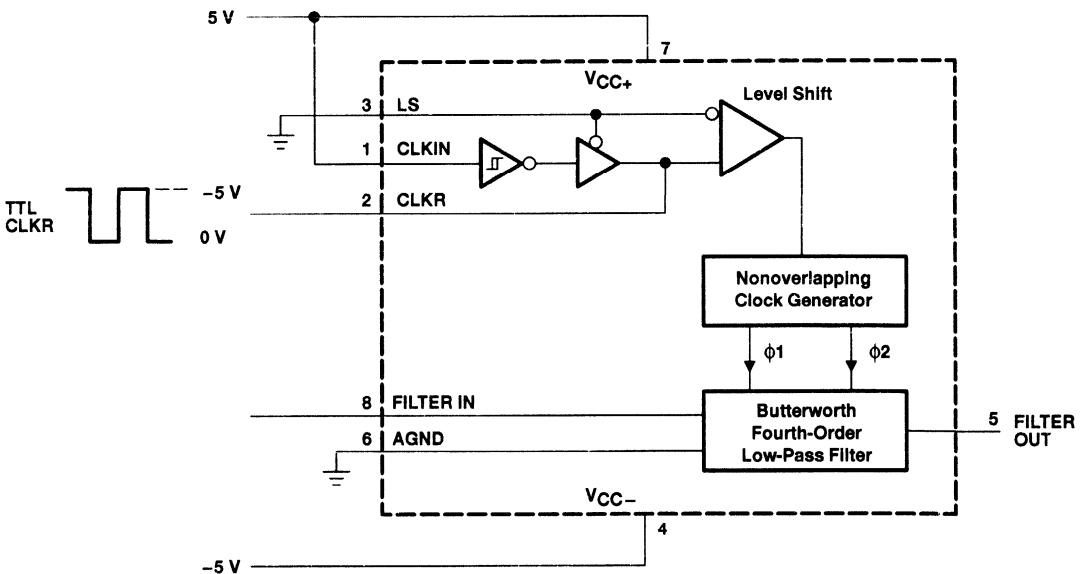
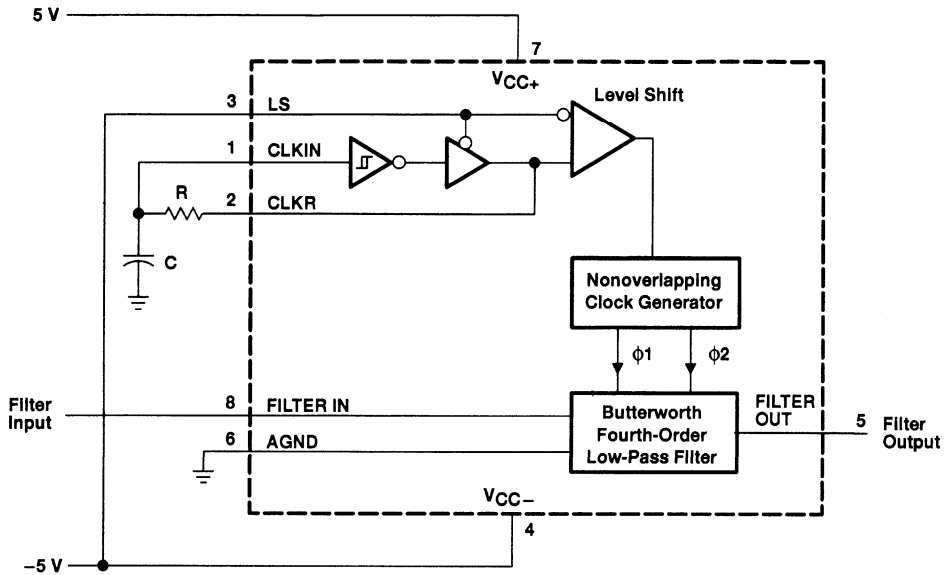


Figure 4. TTL-Clock-Driven Dual-Supply Operation

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APPLICATION INFORMATION



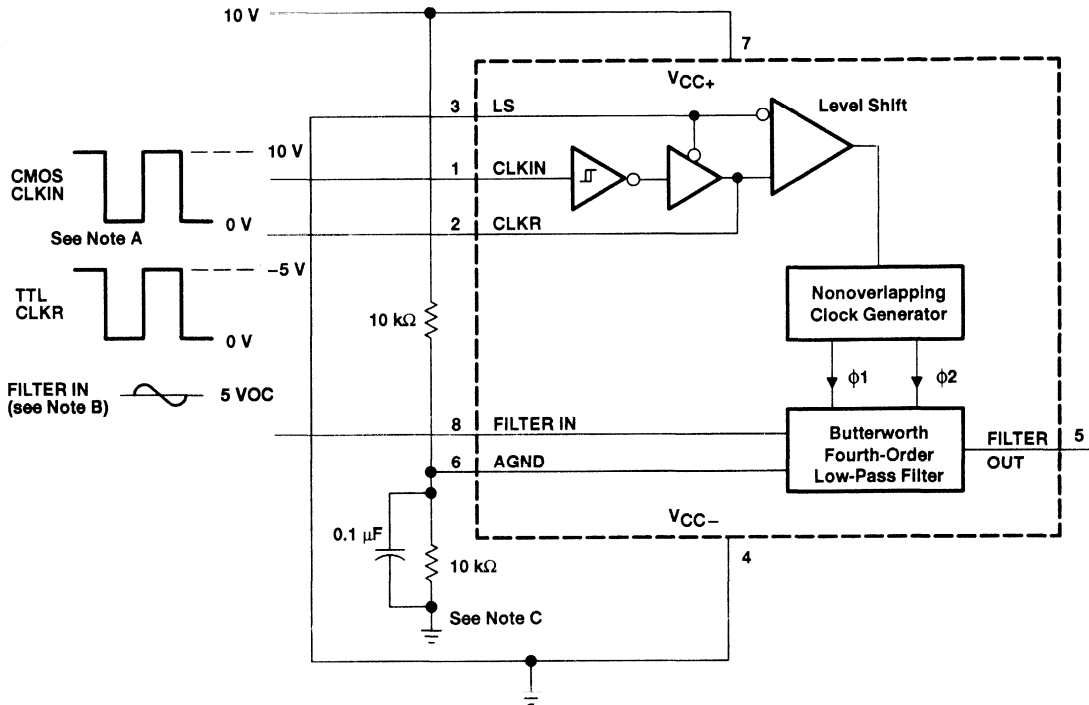
$$f_{\text{clock}} = \frac{1}{RC \times \ln \left[\left(\frac{V_{CC-} - V_{IT-}}{V_{CC-} - V_{IT+}} \right) \left(\frac{V_{IT+}}{V_{IT-}} \right) \right]}$$

For $V_{CC} = 10 \text{ V}$

$$f_{\text{clock}} = \frac{1}{1.69 RC}$$

Figure 5. Self-Clocking Through Schmitt-Trigger Oscillator Dual-Supply Operation

APPLICATION INFORMATION

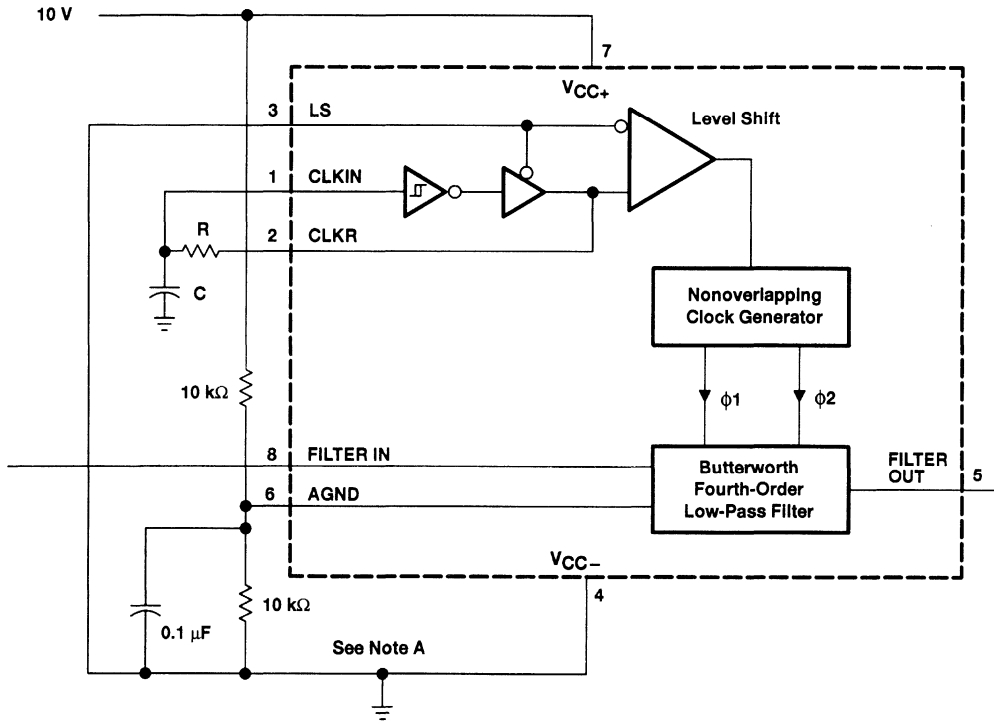


- NOTES: A. The external clock used must be of CMOS level because the clock is input to a CMOS Schmitt trigger.
 B. The filter input signal should be dc-biased to midsupply or ac-coupled to the terminal.
 C. AGND must be biased to midsupply.

Figure 6. External-Clock-Driven Single-Supply Operation

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$$f_{\text{clock}} = \frac{1}{RC \times \ln \left[\left(\frac{V_{CC} - V_{IT-}}{V_{CC} - V_{IT+}} \right) \left(\frac{V_{IT+}}{V_{IT-}} \right) \right]}$$

For $V_{CC} = 10 \text{ V}$

$$f_{\text{clock}} = \frac{1}{1.69 RC}$$

NOTE A: AGND must be biased to midsupply.

Figure 7. Self Clocking Through Schmitt-Trigger Oscillator Single-Supply Operation

APPLICATION INFORMATION

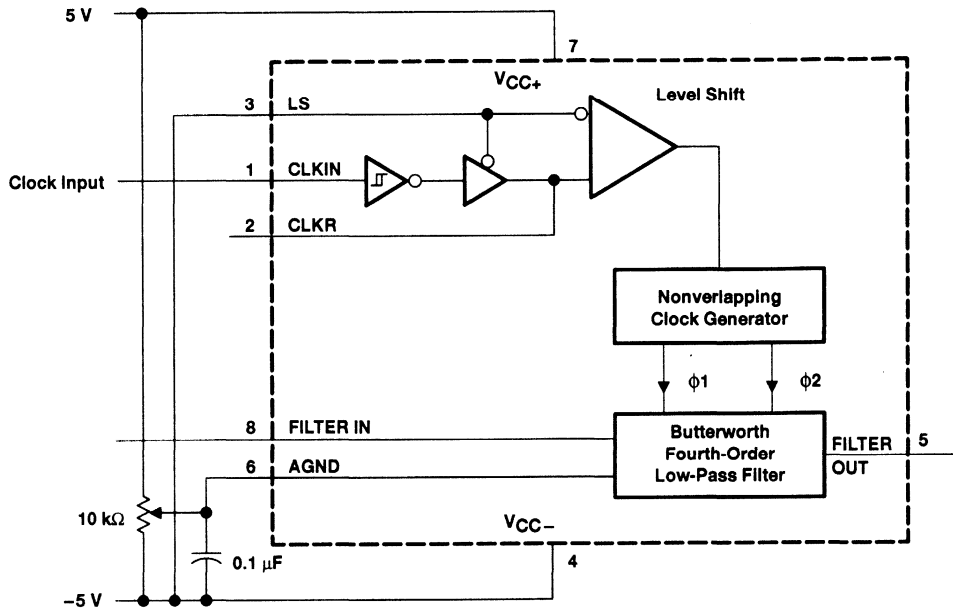


Figure 8. DC Offset Adjustment

TLC29321 HIGH-PERFORMANCE PHASE-LOCKED LOOP

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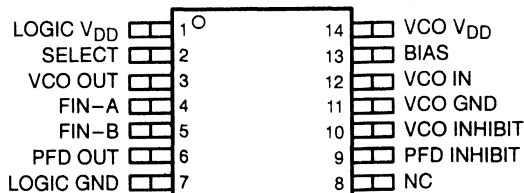
- **Voltage-Controlled Oscillator (VCO) Section:**

Complete Oscillator Using Only One External Bias Resistor (R_{BIAS})

Lock Frequency:
 22 MHz to 50 MHz ($V_{DD} = 5\text{ V} \pm 5\%$,
 $T_A = -20^\circ\text{C}$ to 75°C , $\times 1$ Output)
 11 MHz to 25 MHz ($V_{DD} = 5\text{ V} \pm 5\%$,
 $T_A = -20^\circ\text{C}$ to 75°C , $\times 1/2$ Output)
Output Frequency . . . $\times 1$ and $\times 1/2$ Selectable

- **Phase-Frequency Detector (PFD) Section:**
 High Speed, Edge-Triggered Detector
 With Internal Charge Pump
- Independent VCO, PFD Power-Down Mode
- Thin Small-Outline Package (14 terminal)
- CMOS Technology
- **Typical Applications:**
 Frequency Synthesis
 Modulation/Demodulation
 Fractional Frequency Division
- Application Report Available†
- CMOS Input Logic Level

**PW PACKAGE†
(TOP VIEW)**



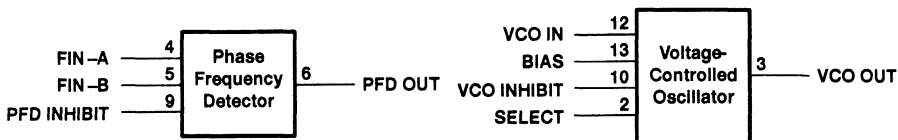
† Available in tape and reel only and ordered as the TLC29321PWLE.

NC – No internal connection

description

The TLC29321 is designed for phase-locked-loop (PLL) systems and is composed of a voltage-controlled oscillator (VCO) and an edge-triggered type phase frequency detector (PFD). The oscillation frequency range of the VCO is set by an external bias resistor (R_{BIAS}). The VCO has a $1/2$ frequency divider at the output stage. The high speed PFD with internal charge pump detects the phase difference between the reference frequency input and signal frequency input from the external counter. Both the VCO and the PFD have inhibit functions, which can be used as a power-down mode. Due to the TLC29321 high speed and stable oscillation capability, the TLC29321 is suitable for use as a high-performance PLL.

functional block diagram



AVAILABLE OPTIONS

T_A	PACKAGE
	SMALL OUTLINE (PW)
-20°C to 75°C	TLC29321PWLE

† TLC2932 Phase-Locked-Loop Building Block With Analog Voltage-Controlled Oscillator and Phase Frequency Detector (SLAA011).

TLC2932I

HIGH-PERFORMANCE PHASE-LOCKED LOOP

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Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
FIN–A	4	I	Input reference frequency $f_{(REF IN)}$ is applied to FIN–A.
FIN–B	5	I	Input for VCO external counter output frequency $f_{(FIN-B)}$. FIN–B is nominally provided from the external counter, see functional block diagram.
LOGIC GND	7		GND for the internal logic.
LOGIC V_{DD}	1		Power supply for the internal logic. This power supply should be separate from VCO V_{DD} to reduce cross-coupling between supplies.
NC	8		No internal connection.
PFD INHIBIT	9	I	PFD inhibit control. When PFD INHIBIT is high, PFD output is in the high-impedance state, see Table 3.
PFD OUT	6	O	PFD output. When the PFD INHIBIT is high, PFD output is in the high-impedance state.
BIAS	13	I	Bias supply. An external resistor (R_{BIAS}) between VCO V_{DD} and BIAS supplies bias for adjusting the oscillation frequency range.
SELECT	2	I	VCO output frequency select. When SELECT is high, the VCO output frequency is $\times 1/2$ and when low, the output frequency is $\times 1$, see Table 1.
VCO IN	12	I	VCO control voltage input. Nominally the external loop filter output connects to VCO IN to control VCO oscillation frequency.
VCO INHIBIT	10	I	VCO inhibit control. When VCO INHIBIT is high, VCO OUT is low (see Table 2).
VCO GND	11		GND for VCO.
VCO OUT	3	O	VCO output. When the VCO INHIBIT is high, VCO output is low.
VCO V_{DD}	14		Power supply for VCO. This power supply should be separated from LOGIC V_{DD} to reduce cross-coupling between supplies.

detailed description

VCO oscillation frequency

The VCO oscillation frequency is determined by an external resistor (R_{BIAS}) connected between the VCO V_{DD} and the BIAS terminals. The oscillation frequency and range depends on this resistor value. The bias resistor value for the minimum temperature coefficient is nominally 3.3 k Ω with 3-V V_{DD} and nominally 2.2 k Ω with 5-V V_{DD} . For the lock frequency range refer to the recommended operating conditions. Figure 1 shows the typical frequency variation and VCO control voltage.

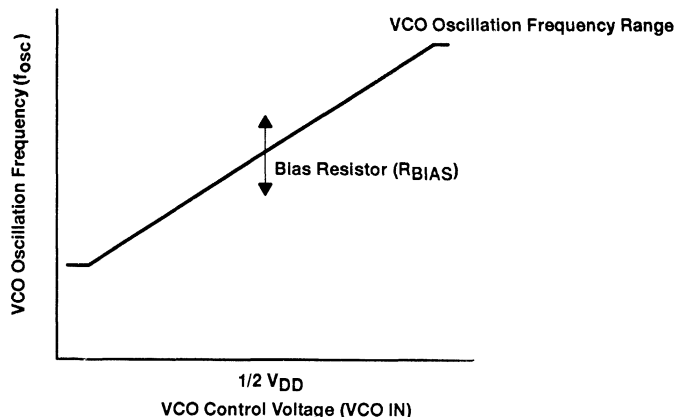


Figure 1. VCO Oscillation Frequency

VCO output frequency 1/2 divider

The TLC2932I SELECT terminal can select between the f_{osc} and $1/2 f_{osc}$ VCO output frequencies as shown in Table 1. The $1/2 f_{osc}$ output should be used for minimum VCO output jitter.

Table 1. VCO Output 1/2 Divider Function

SELECT	VCO OUTPUT
Low	f_{osc}
High	$1/2 f_{osc}$

VCO inhibit function

The VCO has an externally controlled inhibit function which inhibits the VCO output. A high level on the VCO INHIBIT terminal stops the VCO oscillation and powers down the VCO. The output maintains a low level during the power-down mode, refer to Table 2.

Table 2. VCO Inhibit Function

VCO INHIBIT	VCO OSCILLATOR	VCO OUTPUT	$I_{DD}(VCO)$
Low	Active	Active	Normal
High	Stopped	Low level	Power Down

PFD operation

The PFD is a high-speed, edge-triggered detector with an internal charge pump. The PFD detects the phase difference between two frequency inputs supplied to FIN-A and FIN-B as shown in Figure 2. Nominally the reference is supplied to FIN-A, and the frequency from the external counter output is fed to FIN-B. For clock recovery PLL systems, other types of phase detectors should be used.

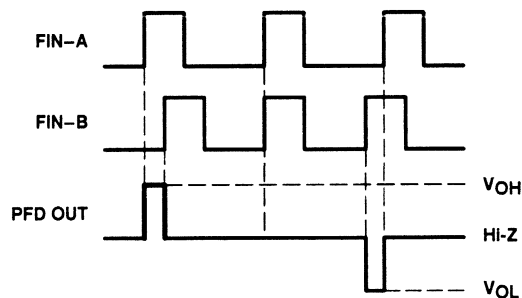


Figure 2. PFD Function Timing Chart

PFD output control

A high level on the PFD INHIBIT terminal places the PFD output in the high-impedance state and the PFD stops phase detection as shown in Table 3. A high level on the PFD INHIBIT terminal also can be used as the power-down mode for the PFD.

Table 3. VCO Output Control Function

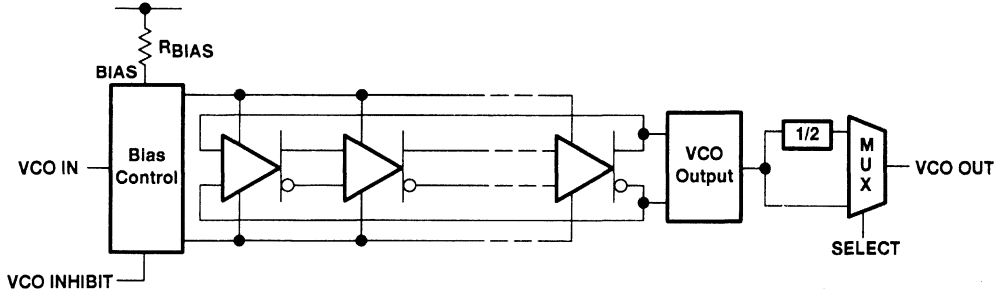
PFD INHIBIT	DETECTION	PFD OUTPUT	$I_{DD}(PFD)$
Low	Active	Active	Normal
High	Stop	Hi-Z	Power Down

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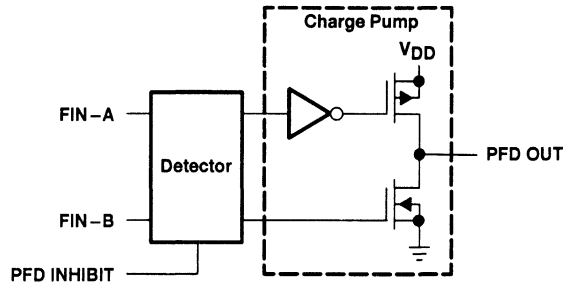
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schematics

VCO block schematic



PFD block schematic



absolute maximum ratings†

Supply voltage (each supply), V_{DD} (see Note 1)	7 V
Input voltage range (each input), V_I (see Note 1)	-0.5 V to $V_{DD} + 0.5$ V
Input current (each input), I_I	± 20 mA
Output current (each output), I_O	± 20 mA
Continuous total dissipation, at (or below) $T_A = 25^\circ\text{C}$	700 mW
Operating free-air temperature range, T_A	-20°C to 75°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltage values are with respect to network GND.

2. For operation above 25°C free-air temperature, derate linearly at the rate of 5.6 mW/ $^\circ\text{C}$.

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recommended operating conditions

PARAMETER		MIN	NOM	MAX	UNIT
Supply voltage, V_{DD} (each supply, see Note 3)	$V_{DD} = 3\text{ V}$	2.85	3	3.15	V
	$V_{DD} = 5\text{ V}$	4.75	5	5.25	
Input voltage, V_I (inputs except VCO IN)		0		V_{DD}	V
Output current, I_O (each output)		0		± 2	mA
VCO control voltage at VCO IN		0.9		V_{DD}	V
Lock frequency ($\times 1$ output)	$V_{DD} = 3\text{ V}$	14		21	MHz
	$V_{DD} = 5\text{ V}$	22		50	
Lock frequency ($\times 1/2$ output)	$V_{DD} = 3\text{ V}$	7		10.5	MHz
	$V_{DD} = 5\text{ V}$	11		25	
Bias resistor, R_{BIAS}	$V_{DD} = 3\text{ V}$	2.2	3.3	4.3	k Ω
	$V_{DD} = 5\text{ V}$	1.5	2.2	3.3	

NOTE 3: It is recommended that the logic supply terminal (LOGIC V_{DD}) and the VCO supply terminal (VCO V_{DD}) should be at the same voltage and separated from each other.

electrical characteristics over recommended operating free-air temperature range, $V_{DD} = 3\text{ V}$ (unless otherwise noted)

VCO section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -2\text{ mA}$	2.4			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$			0.3	V
V_{IT}	Input threshold voltage at SELECT, VCO INHIBIT		0.9	1.5	2.1	V
I_i	Input current at SELECT, VCO INHIBIT	$V_I = V_{DD}$ or GND			± 1	μA
$Z_i(\text{VCO IN})$	Input impedance	VCO IN = $1/2 V_{DD}$		10		M Ω
$I_{DD}(\text{INH})$	VCO supply current (inhibit)	See Note 4		0.01	1	μA
$I_{DD}(\text{VCO})$	VCO supply current	See Note 5		5	15	mA

NOTES: 4. Current into VCO V_{DD} , when VCO INHIBIT = V_{DD} , PFD is inhibited.

5. Current into VCO V_{DD} , when VCO IN = $1/2 V_{DD}$, $R_{BIAS} = 3.3\text{ k}\Omega$, VCO INHIBIT = GND, and PFD is inhibited.

PFD section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -2\text{ mA}$	2.7			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$			0.2	V
I_{OZ}	High-impedance-state output current	PFD INHIBIT = high, $V_I = V_{DD}$ or GND			± 1	μA
V_{IH}	High-level input voltage at FIN-A, FIN-B		2.7			V
V_{IL}	Low-level input voltage at FIN-A, FIN-B				0.5	V
V_{IT}	Input threshold voltage at PFD INHIBIT		0.9	1.5	2.1	V
C_i	Input capacitance at FIN-A, FIN-B			5		pF
Z_i	Input impedance at FIN-A, FIN-B			10		M Ω
$I_{DD}(Z)$	High-impedance-state PFD supply current	See Note 6		0.01	1	μA
$I_{DD}(\text{PFD})$	PFD supply current	See Note 7		0.1	1.5	mA

NOTES: 6. Current into LOGIC V_{DD} , when FIN-A, FIN-B = GND, PFD INHIBIT = V_{DD} , no load, and VCO OUT is inhibited.

7. Current into LOGIC V_{DD} , when FIN-A, FIN-B = 1 MHz ($V_{I(pp)} = 3\text{ V}$, rectangular wave), NC = GND, no load, and VCO OUT is inhibited.

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operating characteristics over recommended operating free-air temperature range, $V_{DD} = 3\text{ V}$ (unless otherwise noted)

VCO section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{osc}	Operating oscillation frequency	$R_{BIAS} = 3.3\text{ k}\Omega$, $V_{CO\ IN} = 1/2 V_{DD}$	15	19	23	MHz
$t_{s(fosc)}$	Time to stable oscillation (see Note 8)	Measured from VCO INHIBIT↓			10	μs
t_r	Rise time	$C_L = 15\text{ pF}$, See Figure 3		7	14	ns
		$C_L = 50\text{ pF}$, See Figure 3		14		
t_f	Fall time	$C_L = 15\text{ pF}$, See Figure 3		6	12	ns
		$C_L = 50\text{ pF}$, See Figure 3		10		
Duty cycle at VCO OUT		$R_{BIAS} = 3.3\text{ k}\Omega$, $V_{CO\ IN} = 1/2 V_{DD}$,	45%	50%	55%	
$\alpha_{(fosc)}$	Temperature coefficient of oscillation frequency	$R_{BIAS} = 3.3\text{ k}\Omega$, $V_{CO\ IN} = 1/2 V_{DD}$, $T_A = -20^\circ\text{C}$ to 75°C		0.04		%/ $^\circ\text{C}$
$k_{SVS(fosc)}$	Supply voltage coefficient of oscillation frequency	$R_{BIAS} = 3.3\text{ k}\Omega$, $V_{CO\ IN} = 1.5\text{ V}$, $V_{DD} = 2.85\text{ V}$ to 3.15 V		0.02		%/mV
Jitter absolute (see Note 9)		$R_{BIAS} = 3.3\text{ k}\Omega$		100		ps

- NOTES: 8. The time period to the stable VCO oscillation frequency after the VCO INHIBIT terminal is changed to a low level.
 9. The LPF circuit is shown in Figure 28 with calculated values listed in Table 7. Jitter performance is highly dependent on circuit layout and external device characteristics. The jitter specification was made with a carefully designed PCB with no device socket.

PFD section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum operating frequency		20			MHz
t_{PLZ}	PFD output disable time from low level	See Figures 4 and 5 and Table 4		21	50	ns
t_{PHZ}	PFD output disable time from high level			23	50	
t_{PZL}	PFD output enable time to low level			11	30	ns
t_{PZH}	PFD output enable time to high level			10	30	
t_r	Rise time	$C_L = 15\text{ pF}$, See Figure 4		2.3	10	ns
t_f	Fall time			2.1	10	ns

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electrical characteristics over recommended operating free-air temperature range, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

VCO section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -2\text{ mA}$	4			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$			0.5	V
V_{IT}	Input threshold voltage at SELECT, VCO INHIBIT		1.5	2.5	3.5	V
I_I	Input current at SELECT, VCO INHIBIT	$V_I = V_{DD}$ or GND			± 1	μA
$Z_i(\text{VCO IN})$	Input impedance	VCO IN = $1/2 V_{DD}$		10		$\text{M}\Omega$
$I_{DD}(\text{INH})$	VCO supply current (inhibit)	See Note 4		0.01	1	μA
$I_{DD}(\text{VCO})$	VCO supply current	See Note 5		15	35	mA

- NOTES: 4. Current into VCO V_{DD} , when VCO INHIBIT = V_{DD} , and PFD is inhibited.
 5. Current into VCO V_{DD} , when VCO IN = $1/2 V_{DD}$, $R_{BIAS} = 3.3\text{ k}\Omega$, VCO INHIBIT = GND, and PFD is inhibited.

PFD section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = 2\text{ mA}$	4.5			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$			0.2	V
I_{OZ}	High-impedance-state output current	PFD INHIBIT = high, $V_I = V_{DD}$ or GND			± 1	μA
V_{IH}	High-level input voltage at FIN-A, FIN-B		4.5			V
V_{IL}	Low-level input voltage at FIN-A, FIN-B				1	V
V_{IT}	Input threshold voltage at PFD INHIBIT		1.5	2.5	3.5	V
C_i	Input capacitance at FIN-A, FIN-B			5		pF
Z_i	Input impedance at FIN-A, FIN-B			10		$\text{M}\Omega$
$I_{DD}(Z)$	High-impedance-state PFD supply current	See Note 6		0.01	1	μA
$I_{DD}(\text{PFD})$	PFD supply current	See Note 7		0.15	3	mA

- NOTES: 6. Current into LOGIC V_{DD} , when FIN-A, FIN-B = GND, PFD INHIBIT = V_{DD} , no load, and VCO OUT is inhibited.
 7. Current into LOGIC V_{DD} , when FIN-A, FIN-B = 1 MHz ($V_{I(\text{PP})} = 5\text{ V}$, rectangular wave), PFD INHIBIT = GND, no load, and VCO OUT is inhibited.

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operating characteristics over recommended operating free-air temperature range, $V_{DD} = 5\text{ V}$ (unless otherwise noted)

VCO section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{osc}	Operating oscillation frequency	$R_{BIAS} = 2.2\text{ k}\Omega$, $VCO\ IN = 1/2\ V_{DD}$	30	41	52	MHz
$t_{s(fosc)}$	Time to stable oscillation (see Note 8)	Measured from VCO INHIBIT↓			10	μs
t_r	Rise time	$C_L = 15\text{ pF}$, See Figure 3		5.5	10	ns
		$C_L = 50\text{ pF}$, See Figure 3		8		
t_f	Fall time	$C_L = 15\text{ pF}$, See Figure 3		5	10	ns
		$C_L = 50\text{ pF}$, See Figure 3		6		
Duty cycle at VCO OUT		$R_{BIAS} = 2.2\text{ k}\Omega$, $VCO\ IN = 1/2\ V_{DD}$,	45%	50%	55%	
$\alpha(fosc)$	Temperature coefficient of oscillation frequency	$R_{BIAS} = 2.2\text{ k}\Omega$, $VCO\ IN = 1/2\ V_{DD}$, $T_A = -20^\circ\text{C}$ to 75°C		0.06		%/ $^\circ\text{C}$
$k_{SVS(fosc)}$	Supply voltage coefficient of oscillation frequency	$R_{BIAS} = 2.2\text{ k}\Omega$, $VCO\ IN = 2.5\text{ V}$, $V_{DD} = 4.75\text{ V}$ to 5.25 V		0.006		%/mV
Jitter absolute (see Note 9)		$R_{BIAS} = 2.2\text{ k}\Omega$		100		ps

NOTES: 8: The time period to the stable VCO oscillation frequency after the VCO INHIBIT terminal is changed to a low level.

9: The LPF circuit is shown in Figure 28 with calculated values listed in Table 7. Jitter performance is highly dependent on circuit layout and external device characteristics. The jitter specification was made with a carefully designed PCB with no device socket.

PFD section

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}	Maximum operating frequency		40			MHz
t_{pLZ}	PFD output disable time from low level	See Figures 4 and 5 and Table 4		21	40	ns
t_{pHZ}	PFD output disable time from high level			20	40	
t_{pZL}	PFD output enable time to low level			7.3	20	ns
t_{pZH}	PFD output enable time to high level			6.5	20	
t_r	Rise time	$C_L = 15\text{ pF}$, See Figure 4		2.3	10	ns
t_f	Fall time			1.7	10	ns

PARAMETER MEASUREMENT INFORMATION

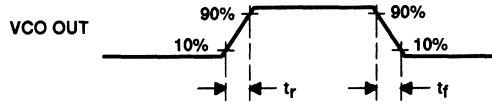
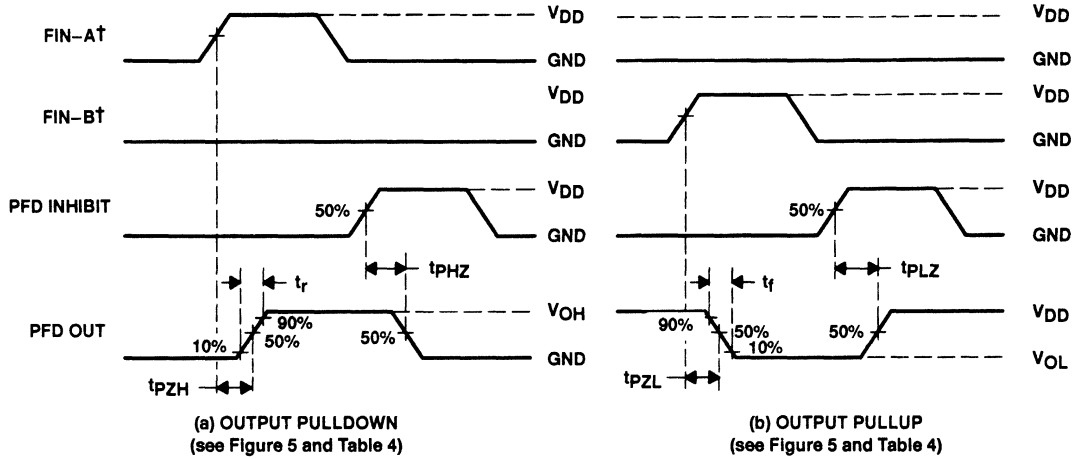


Figure 3. VCO Output Voltage Waveform



† FIN-A and FIN-B are for reference phase only, not for timing.

Figure 4. PFD Output Voltage Waveform

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PARAMETER MEASUREMENT INFORMATION

Table 4. PFD Output Test Conditions

PARAMETER	R_L	C_L	S ₁	S ₂
t _{PZH}	1 k Ω	15 pF	Open	Close
t _{PHZ}				
t _r				
t _{PZL}	1 k Ω	15 pF	Close	Open
t _{PLZ}				
t _f				

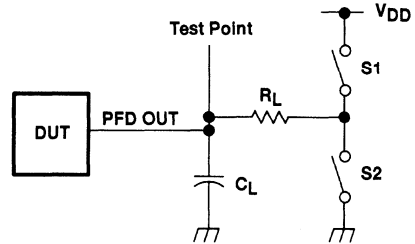


Figure 5. PFD Output Test Conditions

TYPICAL CHARACTERISTICS

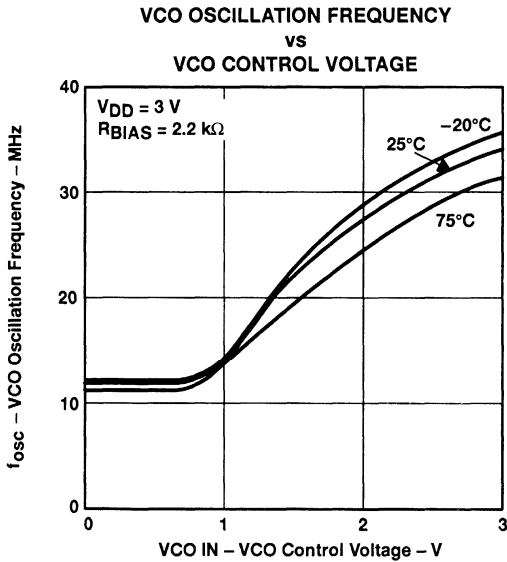


Figure 6

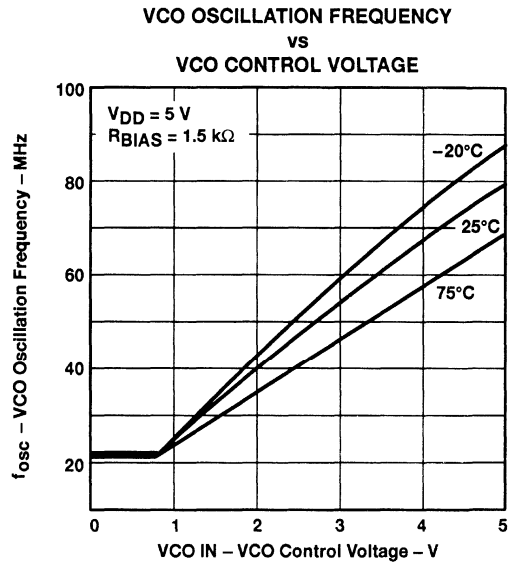


Figure 7

TYPICAL CHARACTERISTICS

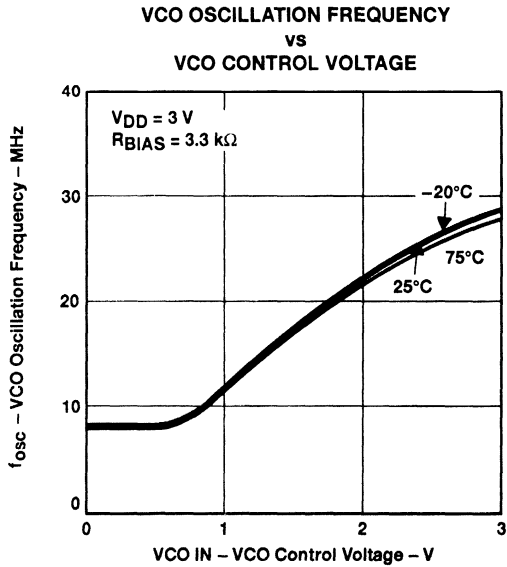


Figure 8

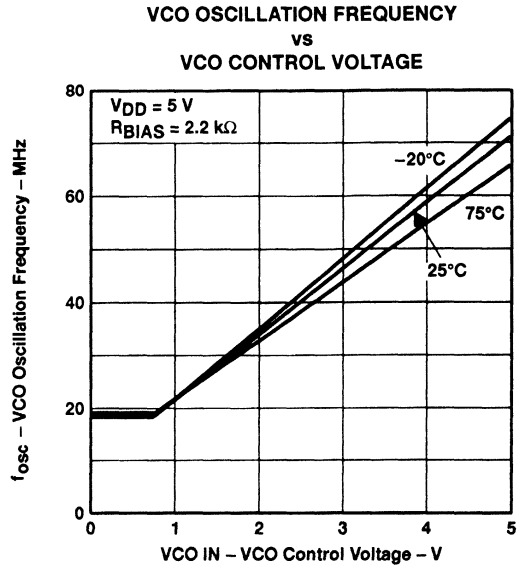


Figure 9

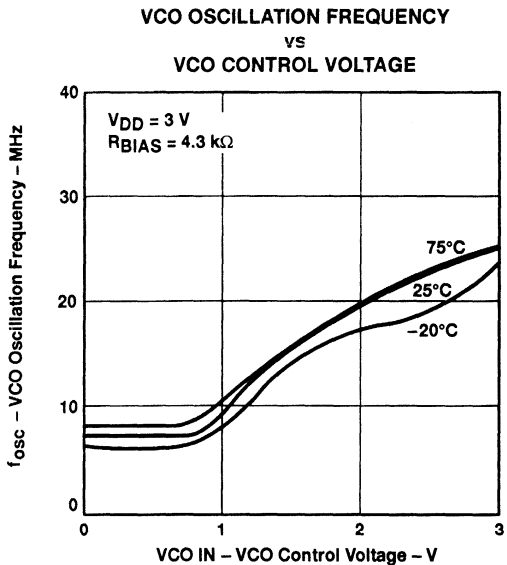


Figure 10

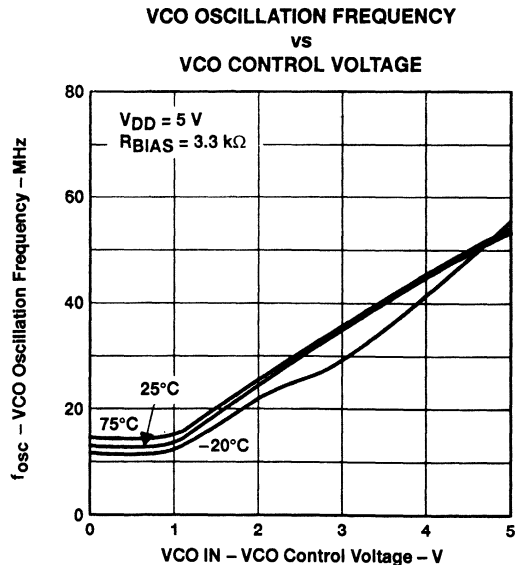


Figure 11

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TYPICAL CHARACTERISTICS

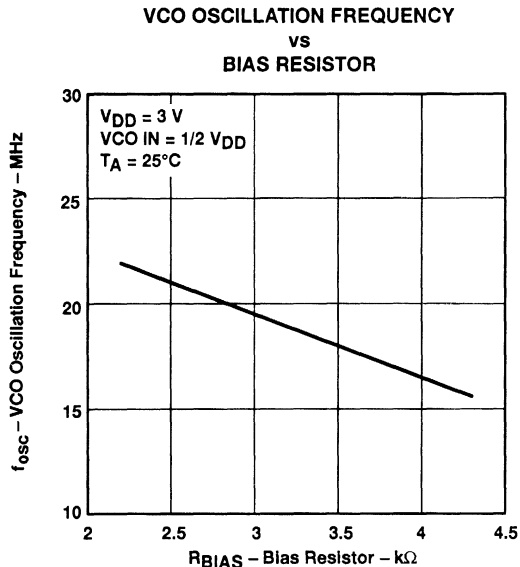


Figure 12

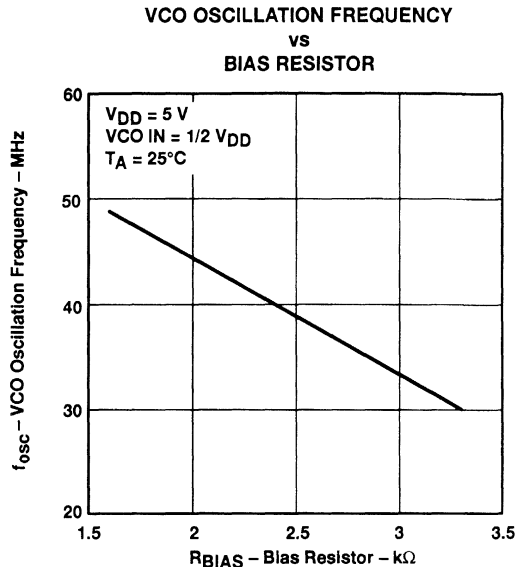


Figure 13

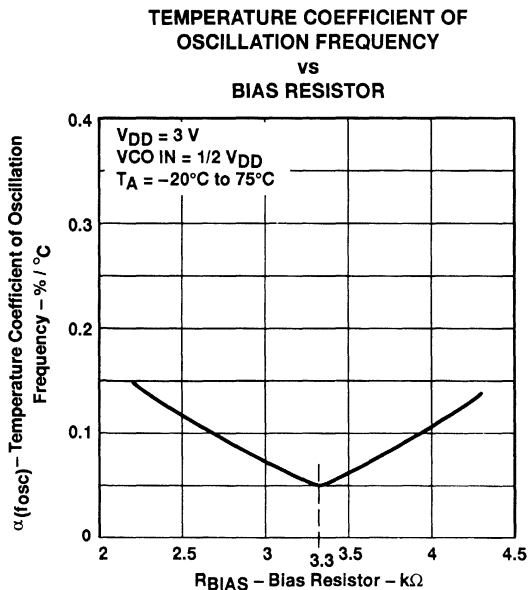


Figure 14

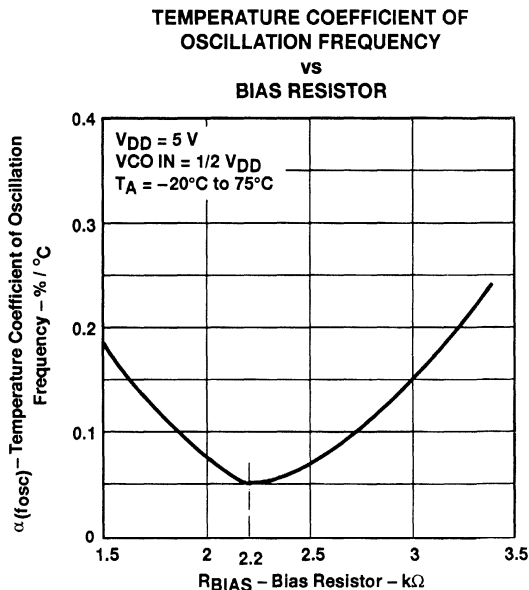


Figure 15

TYPICAL CHARACTERISTICS

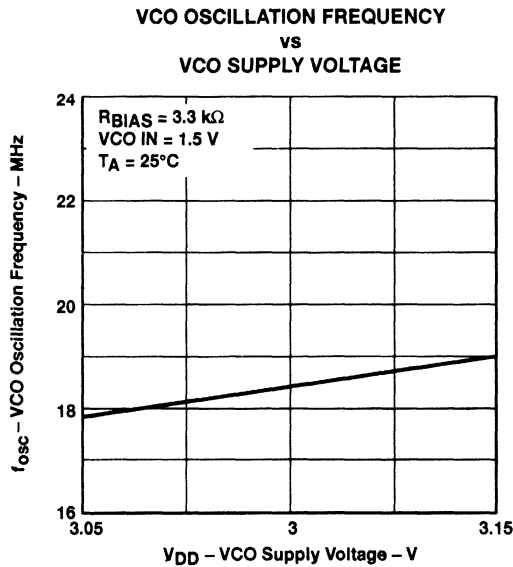


Figure 16

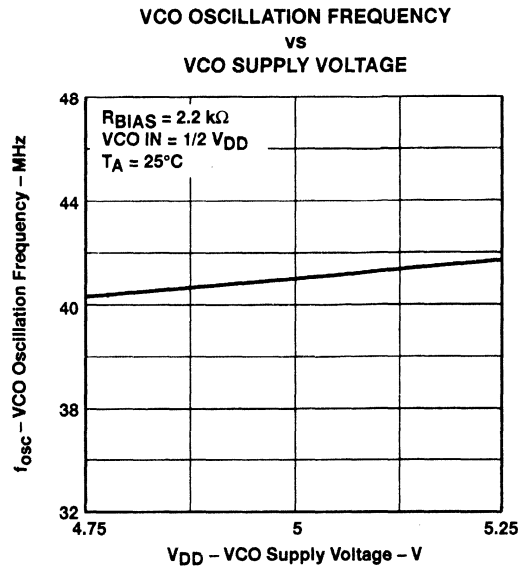


Figure 17

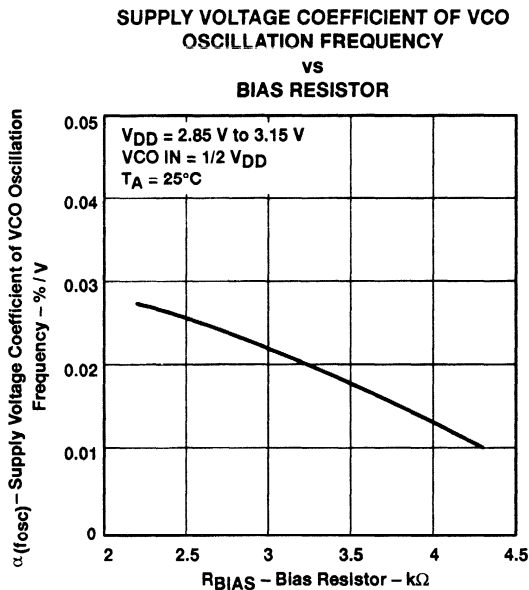


Figure 18

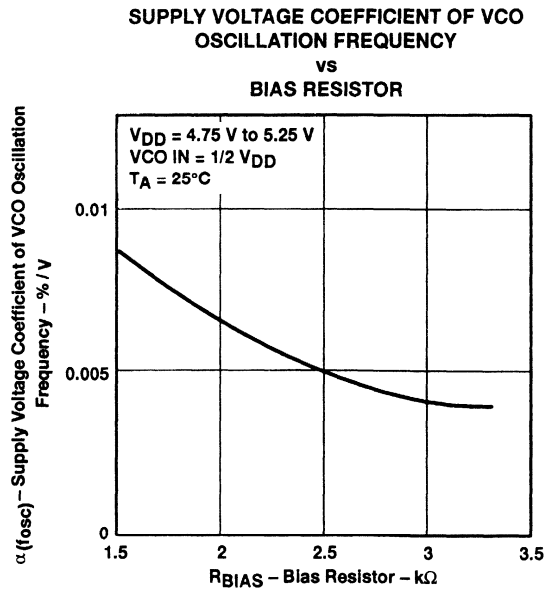


Figure 19

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APPLICATION INFORMATION

RECOMMENDED LOCK FREQUENCY
($\times 1$ OUTPUT)
vs
BIAS RESISTOR

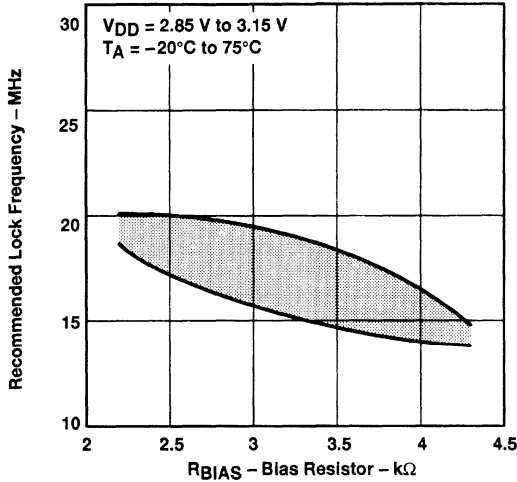


Figure 20

RECOMMENDED LOCK FREQUENCY
($\times 1$ OUTPUT)
vs
BIAS RESISTOR

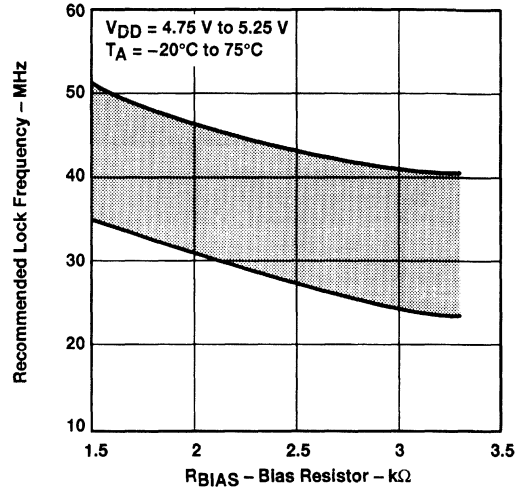


Figure 21

RECOMMENDED LOCK FREQUENCY
($\times 1/2$ OUTPUT)
vs
BIAS RESISTOR

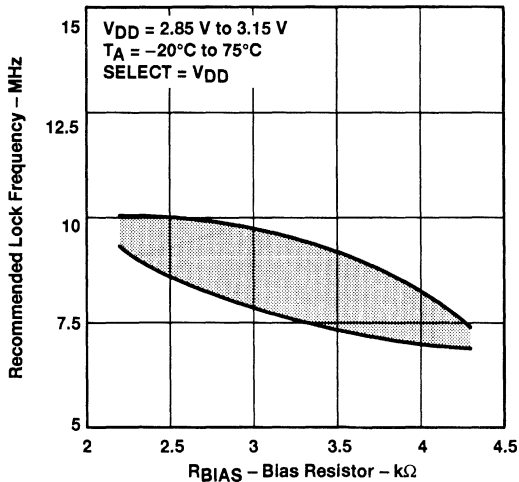


Figure 22

RECOMMENDED LOCK FREQUENCY
($\times 1/2$ OUTPUT)
vs
BIAS RESISTOR

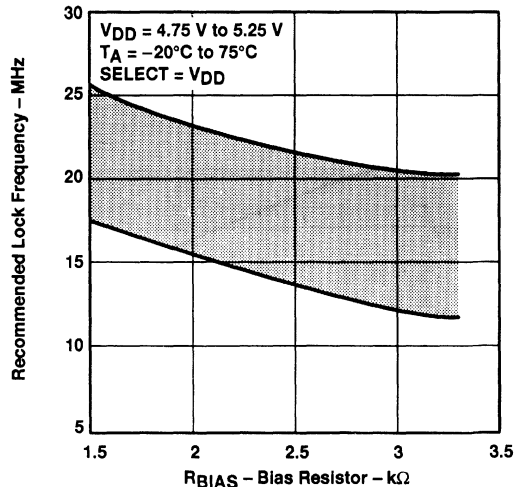


Figure 23

APPLICATION INFORMATION

gain of VCO and PFD

Figure 24 is a block diagram of the PLL. The countdown N value depends on the input frequency and the desired VCO output frequency according to the system application requirements. The K_p and K_V values are obtained from the operating characteristics of the device as shown in Figure 24. K_p is defined from the phase detector V_{OL} and V_{OH} specifications and the equation shown in Figure 24(c). K_V is defined from Figures 8, 9, 10, and 11 as shown in Figure 24(c).

The parameters for the block diagram with the units are as follows:

- K_V : VCO gain (rad/s/V)
- K_p : PFD gain (V/rad)
- K_f : LPF gain (V/V)
- K_N : count down divider gain (1/N)

external counter

When a large N counter is required by the application, there is a possibility that the PLL response becomes slow due to the counter response delay time. In the case of a high frequency application, the counter delay time should be accounted for in the overall PLL design.

RBIAS

The external bias resistor sets the VCO center frequency with $1/2 V_{DD}$ applied to the VCO IN terminal. However, for optimum temperature performance, a resistor value of 3.3 kΩ with a 3-V supply and a resistor value of 2.5 kΩ for a 5-V supply is recommended. For the most accurate results, a metal-film resistor is the better choice but a carbon-composition resistor can be used with excellent results also. A 0.22 μF capacitor should be connected from the BIAS terminal to ground as close to the device terminals as possible.

hold-in range

From the technical literature, the maximum hold-in range for an input frequency step for the three types of filter configurations shown in Figure 25 is as follows:

$$\Delta\omega_H = 0.8 (K_p) (K_V) (K_f(\infty))$$

Where

$K_f(\infty)$ = the filter transfer function value at $\omega = \infty$

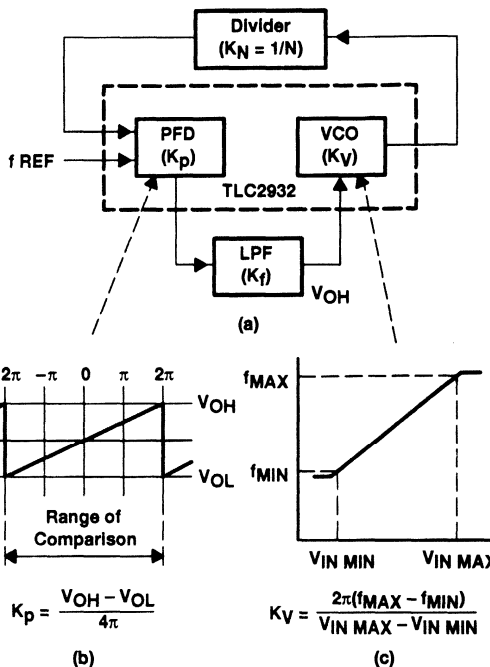


Figure 24. Example of a PLL Block Diagram

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APPLICATION INFORMATION

low-pass-filter (LPF) configurations

Many excellent references are available that include detailed design information about LPFs and should be consulted for additional information. Lag-lead filters or active filters are often used. Examples of LPFs are shown in Figure 25. When the active filter of Figure 25(c) is used, the reference should be applied to FIN-B because of the amplifier inversion. Also, in practical filter implementations, C_f is used as additional filtering at the VCO input. The value of C_f should be equal to or less than one tenth the value of C .

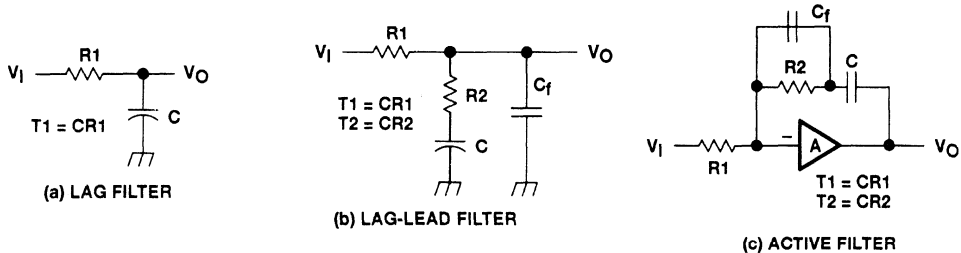


Figure 25. LPF Examples for PLL

the passive filter

The transfer function for the low-pass filter shown in Figure 25(b) is

$$\frac{V_O}{V_{IN}} = \frac{1 + s \cdot T_2}{1 + s \cdot (T_1 + T_2)}$$

Where

$$T_1 = R_1 \cdot C_f \text{ and } T_2 = R_2 \cdot C$$

Using this filter makes the closed loop PLL system a second order type 1 system. The response curves of this system to a unit step are shown in Figure 27.

the active filter

When using the active integrator shown in Figure 25(c), the phase detector inputs must be reversed since the integrator adds an additional inversion. Therefore, the input reference frequency should be applied to the FIN-B terminal and the output of the VCO divider should be applied to the input reference terminal, FIN-A.

The transfer function for the active filter shown in Figure 25(c) is:

$$F(s) = \frac{1 + s \cdot R_2 \cdot C}{s \cdot R_1 \cdot C}$$

Using this filter makes the closed loop PLL system a second-order type 2 system. The response curves of this system to a unit step are shown in Figure 27.

basic design example

The following design example presupposes that the input reference frequency and the required frequency of the VCO are within the respective ranges of the device.

Assume the loop has to have a 100 μs settling time (t_s) with a countdown $N = 8$. Using the Type 1, second order response curves of Figure 26, a value of 4.5 radians is selected for $\omega_n t_s$ with a damping factor of 0.7. This selection gives a good combination for settling time, accuracy, and loop gain margin. The initial parameters are summarized in Table 5. The loop constants, K_V and K_p , are calculated from the data sheet specifications and Table 6 shows these values.

The natural loop frequency is calculated as follows:

Since

$$\omega_n t_s = 4.5$$

Then

$$\omega_n = \frac{4.5}{100 \mu\text{s}} = 45 \text{ k-radians/sec}$$

Table 5. Design Parameters

PARAMETER	SYMBOL	VALUE	UNITS
Division factor	N	8	
Lockup time	t	100	μs
Radian value to selected lockup time	$\omega_n t$	4.5	rad
Damping factor	ζ	0.7	

Table 6. Device Specifications

PARAMETER	SYMBOL	VALUE	UNITS
VCO gain		76.6	Mrad/V/s
f_{MAX}	K_V	50	MHz
f_{MIN}		20	MHz
$V_{\text{IN MAX}}$		5	V
$V_{\text{IN MIN}}$		0.9	V
PFD gain	K_p	0.342357	V/rad

Table 7. Calculated Values

PARAMETER	SYMBOL	VALUE	UNITS
Natural angular frequency	ω_n	45000	rad/sec
$K = (K_V \cdot K_p)/N$		3.277	Mrad/sec
Lag-lead filter			
Calculated value	R1	15870	Ω
Nearest standard value		16000	
Calculated value	R2	308	Ω
Nearest standard value		300	
Selected value	C1	1	μF

TLC2932I HIGH-PERFORMANCE PHASE-LOCKED LOOP

SLAS097B – SEPTEMBER 1994 – REVISED MARCH 1995

APPLICATION INFORMATION

Using the low-pass filter in Figure 25(b) and divider ratio N, the transfer function for phase and frequency are shown in equations 1 and 2. Note that the transfer function for phase differs from the transfer function for frequency by only the divider value N. The difference arises from the fact that the feedback for phase is unity while the feedback for frequency is 1/N.

Hence, transfer function of Figure 24 (a) for phase is

$$\frac{\Phi_2(s)}{\Phi_1(s)} = \frac{K_p \cdot K_V}{N \cdot (T_1 + T_2)} \left[\frac{1 + s \cdot T_2}{s^2 + s \left[1 + \frac{K_p \cdot K_V \cdot T_2}{N \cdot (T_1 + T_2)} \right] + \frac{K_p \cdot K_V}{N \cdot (T_1 + T_2)}} \right] \quad (1)$$

and the transfer function for frequency is

$$\frac{F_{OUT}(s)}{F_{REF}(s)} = \frac{K_p \cdot K_V}{(T_1 + T_2)} \left[\frac{1 + s \cdot T_2}{s^2 + s \cdot \left[1 + \frac{K_p \cdot K_V \cdot T_2}{N \cdot (T_1 + T_2)} \right] + \frac{K_p \cdot K_V}{N \cdot (T_1 + T_2)}} \right] \quad (2)$$

The standard two pole denominator is $D = s^2 + 2 \zeta \omega_n s + \omega_n^2$ and comparing the coefficients of the denominator of equation (1) and (2) with the standard two pole denominator gives the following results.

$$\omega_n = \sqrt{\frac{K_p \cdot K_V}{N \cdot (T_1 + T_2)}}$$

Solving for $T_1 + T_2$

$$T_1 + T_2 = \frac{K_p \cdot K_V}{N \cdot \omega_n^2} \quad (3)$$

and by using this value for $T_1 + T_2$ in equation (3) the damping factor is

$$\zeta = \frac{\omega_n}{2} \cdot \left(T_2 + \frac{N}{K_p \cdot K_V} \right)$$

solving for T_2

$$T_2 = \frac{2 \zeta}{\omega_n} - \frac{N}{K_p \cdot K_V}$$

then by substituting for T_2 in equation (3)

$$T_1 = \frac{K_V \cdot K_p}{N \cdot \omega_n^2} - \frac{2 \zeta}{\omega_n} + \frac{N}{K_p \cdot K_V}$$

APPLICATION INFORMATION

From the circuit constants and the initial design parameters then

$$R2 = \left[\frac{2 \zeta}{\omega_n} - \frac{N}{K_p \cdot K_V} \right] \frac{1}{C_f}$$

$$R1 = \left[\frac{K_p \cdot K_V}{\omega_n^2 \cdot N} - \frac{2 \zeta}{\omega_n} + \frac{N}{K_p \cdot K_V} \right] \frac{1}{C_f}$$

The capacitor, C_f , is usually chosen between 1 μF and 0.1 μF to allow for reasonable resistor values and physical capacitor size. In this example, C_f is chosen to be 1 μF and the corresponding R1 and R2 calculated values are listed in Table 7.

APPLICATION INFORMATION

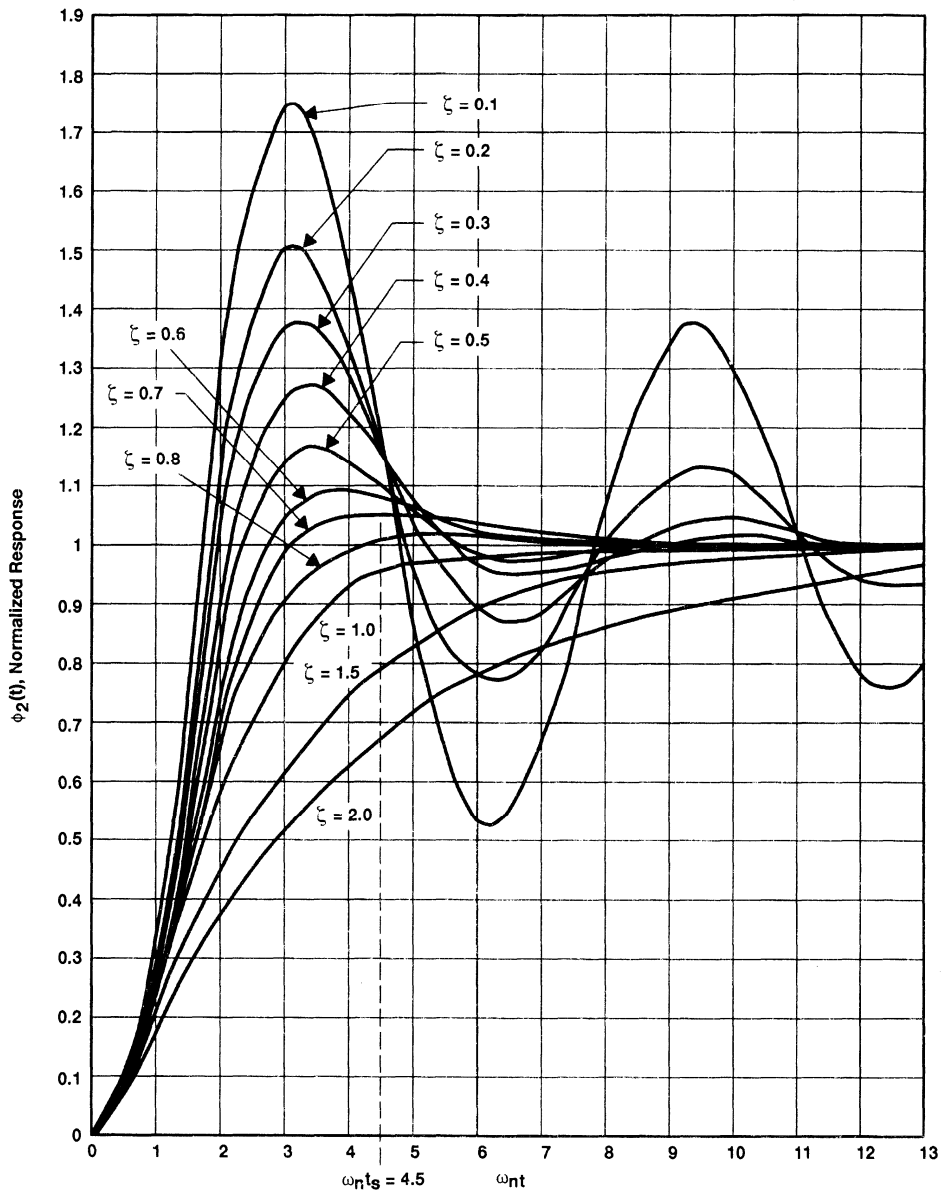


Figure 26. Type 1 Second Order Step Response

APPLICATION INFORMATION

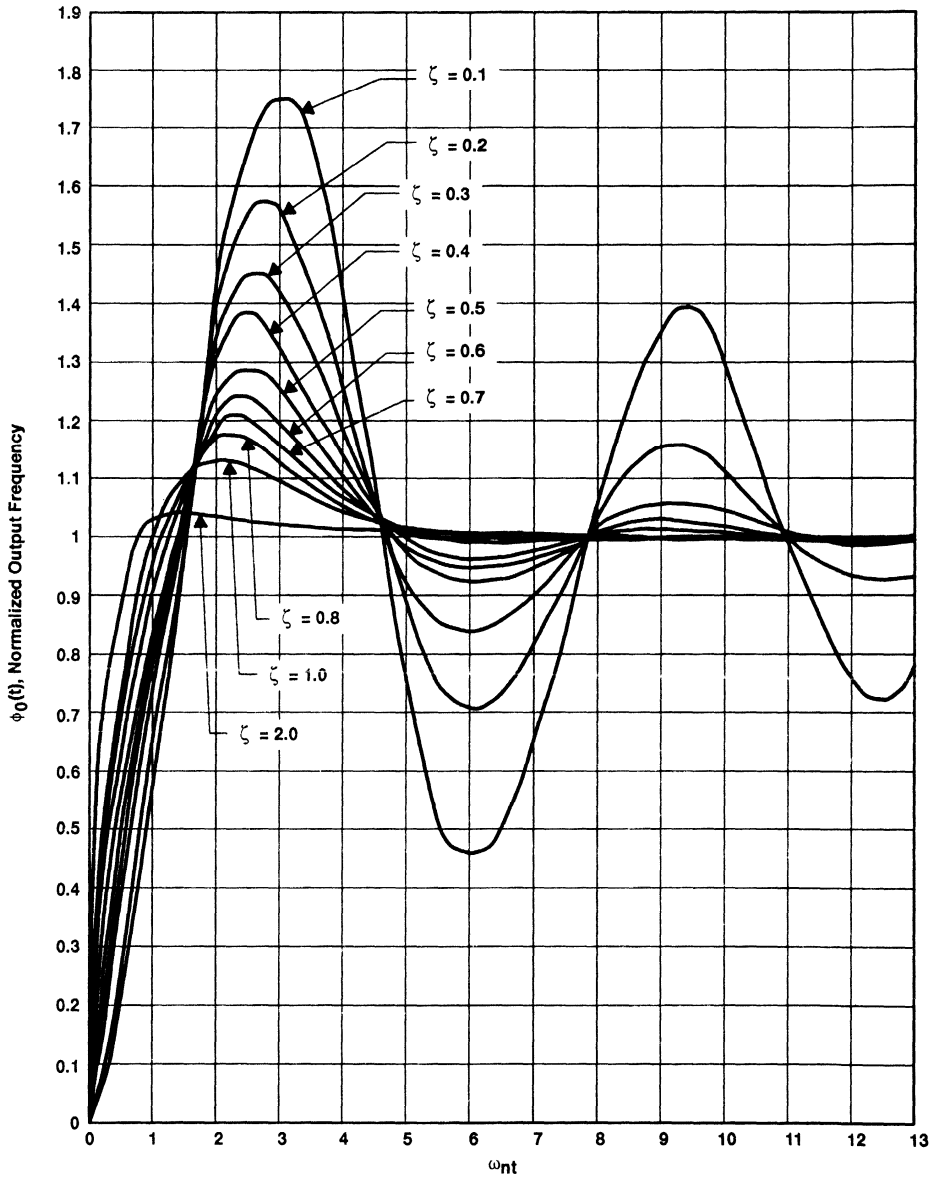


Figure 27. Type 2 Second Order Step Response

TLC2932I HIGH-PERFORMANCE PHASE-LOCKED LOOP

SLAS097B – SEPTEMBER 1994 – REVISED MARCH 1995

APPLICATION INFORMATION

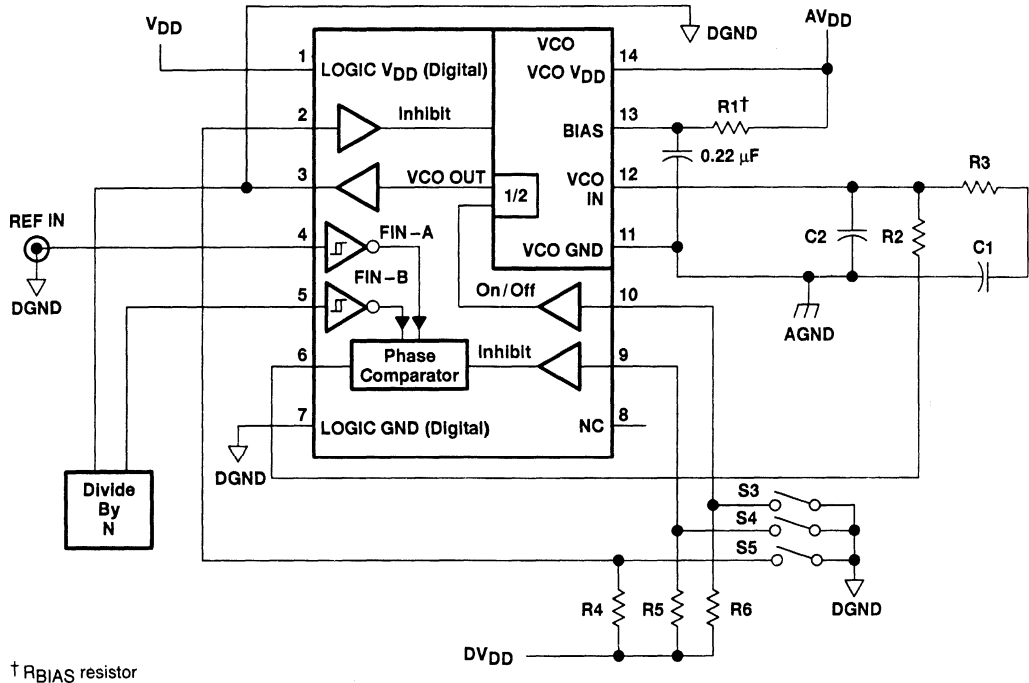


Figure 28. Evaluation and Operation Schematic

PCB layout considerations

The TLC2932I contains a high frequency analog oscillator; therefore, very careful breadboarding and printed-circuit-board (PCB) layout is required for evaluation.

The following design recommendations benefit the TLC2932I user:

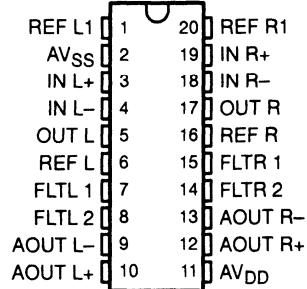
- External analog and digital circuitry should be physically separated and shielded as much as possible to reduce system noise.
- RF breadboarding or RF PCB techniques should be used throughout the evaluation and production process.
- Wide ground leads or a ground plane should be used on the PCB layouts to minimize parasitic inductance and resistance. The ground plane is the better choice for noise reduction.
- LOGIC V_{DD} and VCO V_{DD} should be separate PCB traces and connected to the best filtered supply point available in the system to minimize supply cross-coupling.
- VCO V_{DD} to GND and LOGIC V_{DD} to GND should be decoupled with a 0.1-μF capacitor placed as close as possible to the appropriate device terminals.
- The no-connection (NC) terminal on the package should be connected to GND.

TL32088 DIFFERENTIAL ANALOG BUFFER AMPLIFIER

SLAS123 – MARCH 1995

- Analog Front-End Integrated Circuit for the 18-Bit Stereo Audio Sigma-Delta Analog-to-Digital Converter TLC320AD58C and Equivalent Analog-to-Digital Converters
- Single-Ended to Differential Signal Conversion
- Low Distortion, Low Noise
 - THD+N . . . –100-dB Typ
 - S/N . . . 108-dB Typ
- Adjustable Signal Gain
- 5-V Single Supply Operation
- Internal Voltage Reference
- Operating Temperature . . . –20°C to 70°C

NS PACKAGE
(TOP VIEW)



AVAILABLE OPTIONS

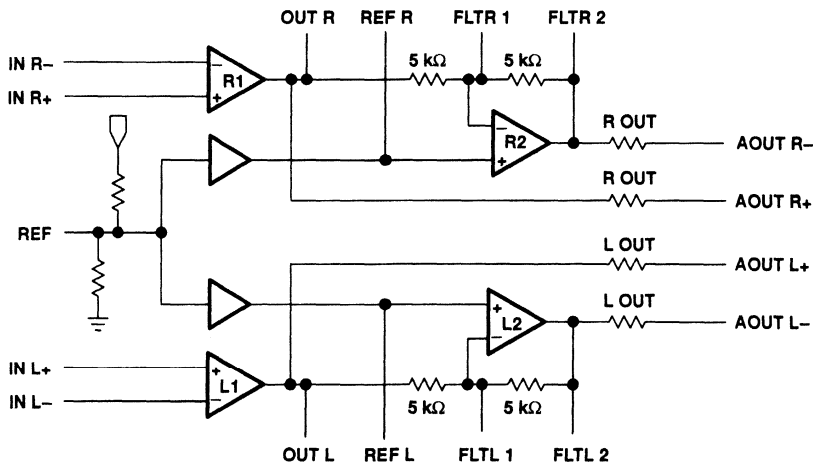
T _A	PACKAGE
	SMALL OUTLINE (NS)
–20°C to 70°C	TL32088INS

description

The TL32088 is an analog signal conditioning integrated circuit built using a proprietary Texas Instruments bipolar process. This device is used for the analog signal input stage of the 18-bit, stereo audio, sigma-delta, analog-to-digital converter (ADC) TLC320AD58C or equivalent converters. The TL32088 converts a single-ended audio signal to a differential signal with externally controlled gain for the input of a sigma-delta ADC, differential-analog signal input. The differential output can be connected to the TLC320AD58C directly. The TL32088 is composed of high performance amplifiers that offer wide output swing with low distortion and low noise. The reference voltage for the internal amplifiers circuit is provided from an internal voltage reference circuit.

The TL32088 operates in a single 5-V supply high end audio system providing wide output swing while maintaining –100-dB THD+N and 108-dB SNR.

functional block diagram



PRODUCT PREVIEW

TL32088 DIFFERENTIAL ANALOG BUFFER AMPLIFIER

SLAS123 – MARCH 1995

absolute maximum rating over operating free-air temperature range (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1)	7 V
Differential input voltage, V_{ID} (see Note 2)	7 V
Input voltage range, V_I (any input) (see Notes 1 and 3)	-0.3 to V_{CC}
Output voltage, V_O	-0.3 to V_{CC}
Output current, I_O	20 mA
Duration of short-circuit current at or below 25°C (output shorted to GND)	unlimited
Continuous total dissipation, P_D ($T_A \leq 25^\circ\text{C}$) (see Note 4)	625 mW
Operating free-air temperature range, T_A	-20°C to 70°C
Storage temperature range, T_{stg}	-65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. All voltage values, except differential voltage, are with respect to GND.
 2. Differential voltage is at the noninverting input with respect to the inverting input.
 3. All input voltage values must not exceed V_{CC} .
 4. Derating factor above $T_A = 25^\circ\text{C}$ is 10 mW/°C.

recommended operating conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC}		5		V
Input voltage range, V_I (see Note 5)	1.1		3.9	V
Operating free-air temperature, T_A	-20		70	°C

NOTE 5: The output voltage is undetermined when the input voltage exceeds recommended input voltage range.

electrical characteristics over recommended operating free-air temperature range, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP	MAX	UNIT
V_{IO}	Input offset voltage	$V_{IC} = 2.5\text{ V}$, $V_O = 2.5\text{ V}$ (AMP L1, R1)	$T_A = 25^\circ\text{C}$		1		mV
			$T_A = -20^\circ\text{C}$ to 70°C		7.5		
I_{IO}	Input offset current	$V_{IC} = 2.5\text{ V}$, $V_O = 2.5\text{ V}$ (AMP L1, R1)	$T_A = 25^\circ\text{C}$		5		nA
			$T_A = -20^\circ\text{C}$ to 70°C		150		
I_{IB}	Input bias current	$V_{IC} = 2.5\text{ V}$, $V_O = 2.5\text{ V}$ (AMP L1, R1)	$T_A = 25^\circ\text{C}$		20		nA
			$T_A = -20^\circ\text{C}$ to 70°C				
V_{IC}	Common-mode input voltage	$V_O \leq 7.5\text{ mV}$ (AMP L1, R1)	$T_A = 25^\circ\text{C}$	0.9		4.1	V
			$T_A = -20^\circ\text{C}$ to 70°C	1.1		3.9	
V_{OM+}	Maximum positive-peak output voltage		$T_A = -20^\circ\text{C}$ to 70°C	4.4			V
V_{OM-}	Maximum negative-peak output voltage		$T_A = -20^\circ\text{C}$ to 70°C			0.6	V
A_{vd}	Differential voltage amplification	$V_O = 2.5\text{ V} \pm 1\text{ V}$ (AMP L1, R1)	$T_A = 25^\circ\text{C}$		60		dB
CMRR	Common-mode rejection ratio	$V_O = 2.5\text{ V} \pm 5\text{ V}$ (AMP L1, R1)	$T_A = 25^\circ\text{C}$		85		dB
V_{ref}	Reference voltage		$T_A = -20^\circ\text{C}$ to 70°C	2.45	2.5	2.55	V
E_G	Gain error	See Note 6	$T_A = -20^\circ\text{C}$ to 70°C			$\pm 3\%$	
r_o	Output resistance		$T_A = 25^\circ\text{C}$		50		Ω
I_{CC}	Supply current (both channels)	$V_O = 2.5\text{ V}$, No load	$T_A = 25^\circ\text{C}$			15	mA
			$T_A = -20^\circ\text{C}$ to 70°C			18	

NOTE 6: Gain error is between OUT L and FLTL 1, OUT R and FLTR 1.

PRODUCT PREVIEW



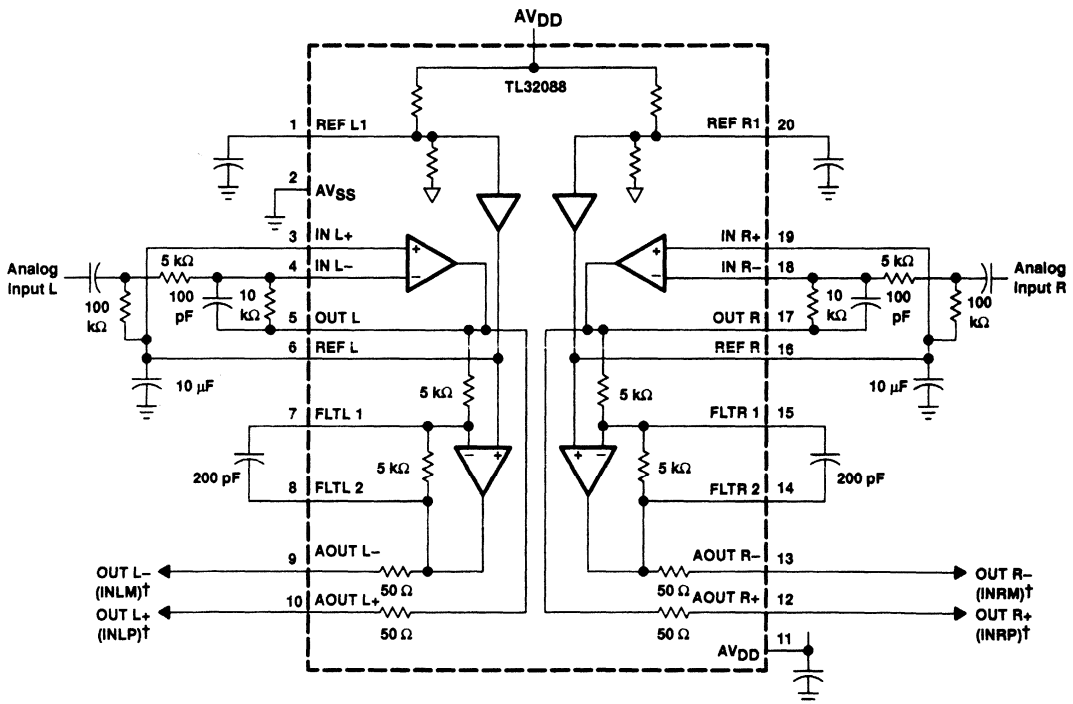
TL32088 DIFFERENTIAL ANALOG BUFFER AMPLIFIER

SLAS123 – MARCH 1995

operating characteristics over recommended operating free-air temperature range, $V_{CC} = 5\text{ V}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
SR Slew rate	$A_V = 1$, $V_I = 2.5\text{ V} + 0.5\text{ V (AMP L1, R1)}$		3		$\text{V}/\mu\text{s}$
B_1 Unity-gain bandwidth	AMP L1, R1		7		MHz
SNR Signal-to-noise ratio (EIAJ)	A-Weight test circuit		108		dB
THD+N Total harmonic distortion plus noise	$V_{O(PP)} = 3.2\text{ V}$, $f = 1\text{ kHz}$, BW = 10 Hz to 20 kHz test circuit		-100		dB

APPLICATION INFORMATION



† TLC320AD58C input terminals.

Figure 1. TL32088 to TLC320AD58C Connections

PRODUCT PREVIEW

General Information	1
General purpose ADCs	2
General Purpose DACs	3
DSP Analog Interface and Conversion	4
Special Functions	5
Video Interface Palettes	6
Data Manuals	7
Application Reports	8
Mechanical Data	9
Appendix	A



Video Interface Palettes

TLC34058 256 × 24 COLOR PALETTE

XLAS050 – APRIL 1995

- CMOS Technology
- 135-MHz Pipelined Architecture
- Available Clock Rate . . . 80, 110, 135 MHz
- Dual-Port Color RAM
256 Words x 24 Bits
- Bit-Plane Read and Blink Masks
- EIA RS-343-A Compatible Outputs
- Functionally Interchangeable With
Brooktree® Bt458
- Direct Interface to SMJ340xx Graphics
Processors (110M)
- Direct Interface to TMS340XX Graphics
Processors
- Standard Microprocessor Unit (MPU)
Palette Interface
- Multiplexed-TTL Pixel Ports
- Triple Digital-to-Analog Converters (DACs)
- Dual-Port Overlay Registers . . . 4 × 24 Bits
- 5-V Power Supply
- Data Sheet Available†

description

The TLC34058 color-palette integrated circuit is specifically developed for high-resolution color graphics in such applications as CAE/CAD/CAM, image processing, and video reconstruction. The architecture provides for the display of 1280 × 1024 bit-mapped color graphics (up to eight bits per pixel resolution) with two bits of overlay information. The TLC34058 has a 256-word × 24-bit RAM used as a lookup table with three 8-bit, video, D/A converters.

On-chip features such as high-speed pixel clock logic minimize costly ECL interface. Multiple pixel ports and internal multiplexing provide TTL-compatible interface (up to 32 MHz) to the frame buffer while maintaining sophisticated color graphic data rates (up to 135 MHz). Programmable blink rates, bit plane masking and blinking, color overlay capability, and a dual-port palette RAM are other key features. The TLC34058 generates red, green, and blue signals compatible with EIA RS-343-A and can drive 75-Ω coaxial cables terminated at each end without external buffering.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE		
			CERAMIC GRID ARRAY (GA)	PLASTIC CHIP CARRIER (FN)	QUAD FLATPACK (HFG)
0°C to 70°C	80 MHz	8 Bits	–	TLC34058-80FN	–
	110 MHz	8 Bits	–	TLC34058-110FN	–
	135 MHz	8 Bits	–	TLC34058-135FN	–
–55°C to 125°C	110 MHz	8 Bits	TLC34058-110MGA	–	TLC34058-110MHFG

† For the complete data sheet, refer to the Graphics and Imaging Data Book (SLAD002).
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standard warranty. Production processing does not necessarily include
testing of all parameters.



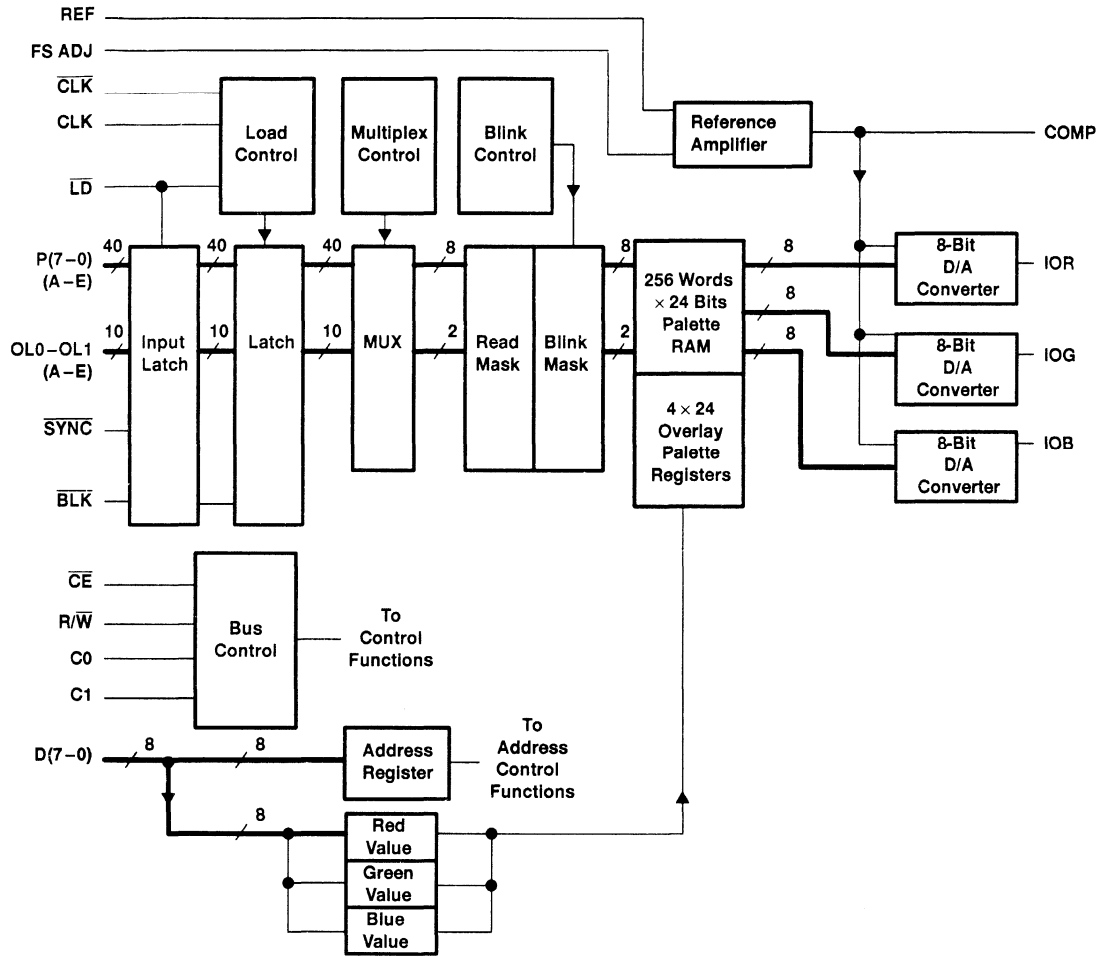
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TLC34058 256 × 24 COLOR PALETTE

XLAS050 – APRIL 1995

functional block diagram



TLC34074
VIDEO INTERFACE
DIGITAL-TO-ANALOG CONVERTER
 XLAS056 – MAY 1995

- Versatile Multiplexing Interface Allows Lower Pixel Bus Rate
- High Level of Integration Provides Lower System Cost and Complexity
- Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats
- Directly Interfaces to TMS34010/TMS34020 and Other Graphics Processors
- Single 8-Bit D/A Converters
- Low Cost Monochrome and Gray-Scale System
- Pin Compatible With TLC34075 and TLC34076
- 135-, 170-, and 200-MHz Versions
- On-Chip Voltage Reference
- RS-343A-Compatible Outputs
- TTL-Compatible Inputs
- Standard MPU Interface
- On-Chip Clock Selection
- Directly Interfaces to Video RAM
- Supports Split Shift-Register Transfers
- TIGA™ Software-Standard Compatible
- CMOS Technology
- Data Manual Available†

description

The TLC34074 video interface DAC (VID) is designed for monochrome and gray-scale graphics systems, providing lower system cost with a higher level of integration by incorporating all the high-speed timing, synchronizing, and multiplexing logic usually associated with graphics systems into one device, thus greatly reducing chip count. Since all high-speed signals (excluding the clock source) are contained on-chip, RF noise considerations are simplified. Maximum flexibility is provided through the pixel multiplexing scheme, which allows for 32-, 16-, 8-, and 4-bit pixel buses to be accommodated without any circuit modification. This enables the system to be easily reconfigured for varying amounts of available video RAM. Additionally, data can be split into 1, 2, 4, or 8-bit gray-scale.

The TLC34074 is also designed to be terminal compatible with the TLC34075 and TLC34076 video interface palettes. Therefore, a single graphics design can be configured into a color or black-and-white system by using either the TLC34075/076 or the TLC34074 to reduce the system cost and increase the resolution. Like the TLC34076, the TLC34074 can be programmed for little or big-endian data format for the pixel bus frame buffer interface.

The TLC34074 has an 8-bit video digital-to-analog converter (DAC) capable of directly driving a doubly terminated 75-Ω line. Sync generation can be incorporated onto the output channel when so enabled. Hsync and Vsync are fed through the device and optionally inverted to indicate screen resolution to the monitor. Bit stuffing logic repeats the intended gray-scale pattern to the least significant bits when the gray-scale is not 8 bits wide. This allows the 8-bit DAC to achieve full RS-343A output levels while maintaining uniform linearity for all codes.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			PLASTIC CHIP CARRIER (FN)
0°C to 70°C	135 MHz	8 Bits	TLC34074-135FN
	170 MHz	8 Bits	TLC34074-170FN
	200 MHz	8 Bits	TLC34074-200FN

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TLC34074 VIDEO COLOR PALETTE

XLAS056 – MAY 1995

description (continued)

Clocking is provided through one of four inputs (3 TTL- and 1 ECL/TTL-compatible) and is software selectable. The video and shift-clock outputs provide a software-selected divide ratio of the chosen clock input.

The TLC34074 can be connected directly to the serial port of VRAM devices, eliminating the need for any discrete logic. Support for split shift-register transfers is also provided.

functional block diagram

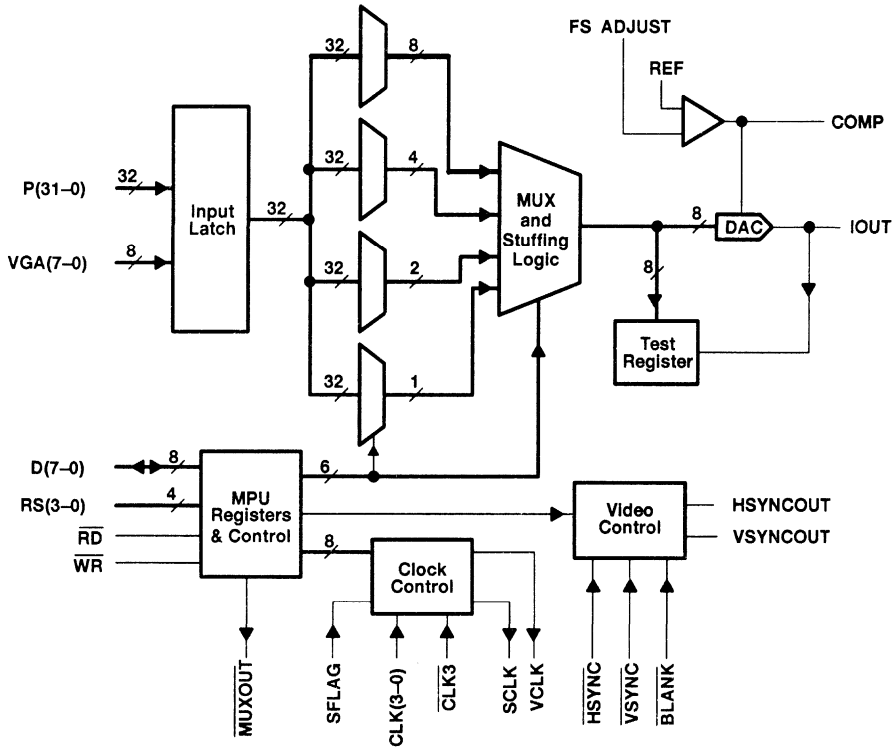


Figure 1. Functional Block Diagram

- Versatile Multiplexing Interface Allows Lower Pixel Bus Rate
- High Level of Integration Provides Lower System Cost and Complexity
- Direct VGA Pass-Through Capability
- Directly Interfaces to TMS34010/TMS34020 and Other Graphics Processors
- Triple 8-Bit D/A Converters
- 66-, 85-, 110, and 135-MHz Versions
- 256-Word Color Palette RAM
- Palette Page Register
- On-Chip Voltage Reference
- RS-343A-Compatible Outputs
- TTL-Compatible Inputs
- Standard MPU Interface
- Pixel Word Mask
- On-Chip Clock Selection
- True Color (Direct Addressing) Mode
- Directly Interfaces to Video RAM
- Supports Split Shift Register Transfers
- Software Downward-Compatible With INMOS IMSG176/8 and Brooktree™ Bt476/8 Color Palettes
- TIGA™ Software-Standard Compatible
- CMOS Technology
- Data Manual Available†

description

The TLC34075A video interface palette (VIP) is designed to provide lower system cost with a higher level of integration by incorporating all the high-speed timing, synchronizing, and multiplexing logic usually associated with graphics systems into one device, thus greatly reducing chip count. Since all high-speed signals (excluding the clock source) are contained on-chip, RF noise considerations are simplified. Maximum flexibility is provided through the pixel multiplexing scheme, which allows for 32-, 16-, 8-, and 4-bit pixel buses to be accommodated without any circuit modification. This enables the system to be easily reconfigured for varying amounts of available video RAM. Data can be split into 1-, 2-, 4-, or 8-bit planes. The TLC34075A is software-compatible with the INMOS IMSG176/8 and Brooktree Bt476/8 color palettes.

The TLC34075A features a separate VGA bus that allows data from the feature connector of most VGA-supported personal computers to be fed directly into the palette without the need for external data multiplexing. This allows a replacement graphics board to remain downward compatible by utilizing the existing graphics circuitry often located on the motherboard. The TLC34075A also provides a true-color mode in which 24 (3 by 8) bits of color information are transferred directly from the pixel port to the DACs. This mode of operation supplies an overlay function using the 8 remaining bits of the pixel bus.

The TLC34075A has a 256-by-24 color lookup table with triple, 8-bit video, D/A converters capable of directly driving a doubly terminated, 75-Ω line. Sync generation is incorporated on the green output channel. HSYNC and VSYNC are fed through the device and optionally inverted to indicate screen resolution to the monitor. A palette page register provides the additional bits of palette address when 1-, 2-, or 4-bit planes are used. This allows the screen colors to be changed with only one MPU write cycle.

Clocking is provided through one of four or five inputs (three TTL- and either one ECL- or two TTL-compatible) and is software selectable. The video and shift clock outputs provide a software-selected divide ratio of the chosen clock input.

The TLC34075A can be connected directly to the serial port of VRAM devices, eliminating the need for any discrete logic. Support for split shift-register transfers is also provided.

The TLC34075A is an optimized version of the original TLC34075 video interface palette. Because all of the critical speed paths have been strengthened on the device, a slightly higher supply current specification is required. The new specification also includes revised SCLK/VCLK timing and a clock-counter reset function.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TIGA is a trademark of Texas Instruments Incorporated.

TLC34075A VIDEO INTERFACE PALETTE

XLAS058 – MAY 1995

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			PLASTIC CHIP CARRIER (FN)
0°C to 70°C	66 MHz	8 Bits	TLC34075-66AFN
	85 MHz	8 Bits	TLC34075-85AFN
	110 MHz	8 Bits	TLC34075-110AFN
	135 MHz	8 Bits	TLC34075-135AFN



functional block diagram

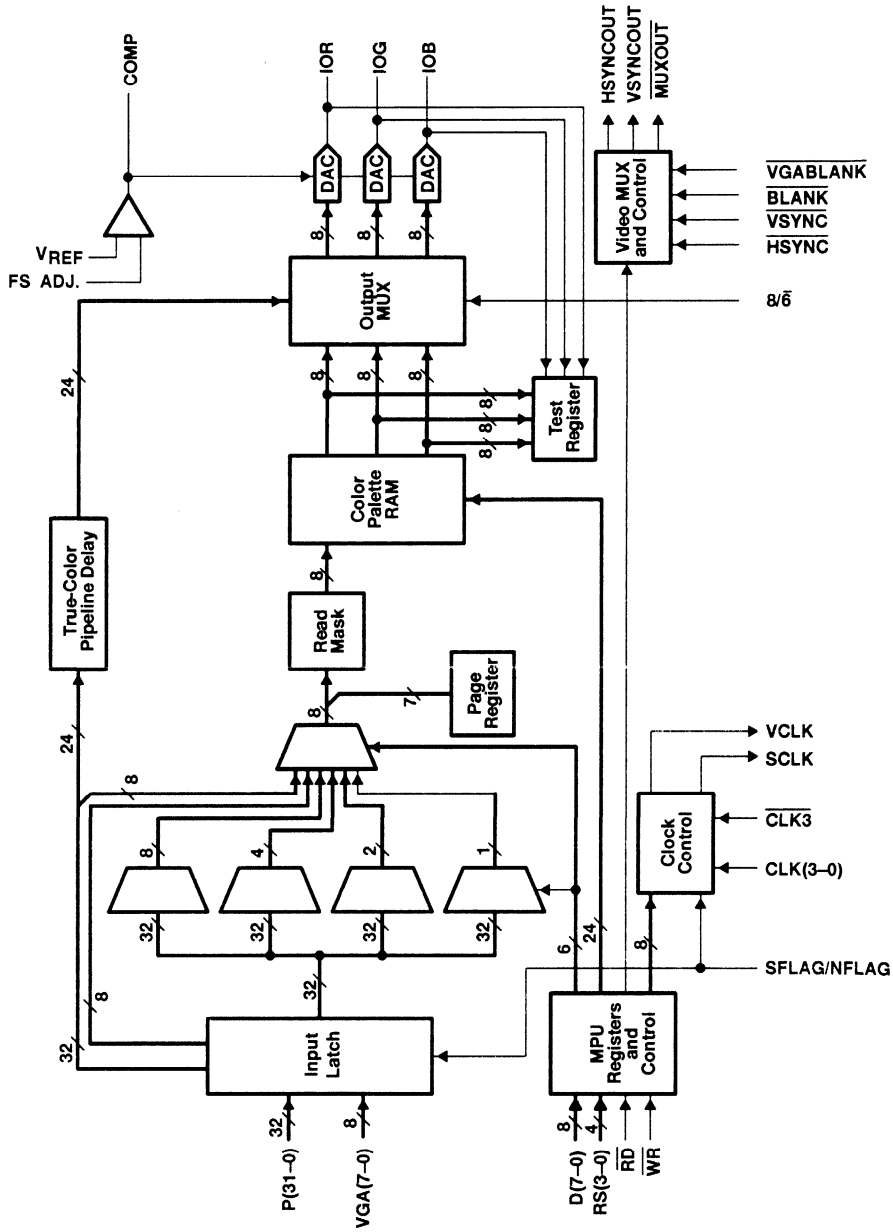


Figure 1. Functional Block Diagram

- CMOS Technology
- Versatile Multiplexing Interface Allows Lower Pixel Bus Rate
- High Level of Integration Provides Lower System Cost and Complexity
- Direct VGA Pass-Through Capability
- Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats
- True-Color (Direct Addressing) Modes Support Various 24- and 16-Bit Formats
- XGA™-Format Compatible (5-6-5)
- TARGA™-Format Compatible (5-5-5)
- Directly Interfaces to TMS34010/TMS34020 and Other Graphics Processors
- Triple 8-Bit D/A Converters
- 85-, 110-, 135-, and 170- MHz Versions
- 256-Word Color Palette RAM
- Palette Page Register
- On-Chip Voltage Reference
- RS-343A-Compatible Outputs
- TTL-Compatible Inputs
- Standard MPU Interface
- Pixel Word Mask
- On-Chip Clock Selection
- Directly Interfaces to Video RAM
- Supports Split Shift-Register Transfers
- Software Downward-Compatible With INMOS MSG176/8 and Brooktree™ BT476/8 Color Palettes
- TIGA™ Software-Standard Compatible
- Data Manual Available†

description

The TLC34076 video interface palette (VIP) is designed to provide lower system cost with a higher level of integration. The device incorporates all of the high-speed timing, synchronization, and multiplexing logic usually associated with graphics systems into one device, thus greatly reducing chip count. Since all high-speed signals (excluding the clock source) are contained on-chip, RF noise considerations are simplified. Maximum flexibility is provided through the pixel multiplexing scheme, which allows for 32-, 16-, 8-, and 4-bit pixel buses to be accommodated without any circuit modification. This enables the system to be easily reconfigured for varying amounts of available video RAM. Data can be split into 1-, 2-, 4-, or 8-bit planes. The TLC34076 is software-compatible with the MSG176/8 and Brooktree BT476/8 color palettes.

The TLC34076 VIP is terminal-for-terminal compatible with the TLC34075 VIP but contains additional 24- and 16-bit true-color modes as well as the ability to select little- or big-endian data formats for the pixel bus frame-buffer interface.

The TLC34076 features a separate video graphics adapter (VGA) bus that allows data from the feature connector of most VGA-supported personal computers to be fed directly into the palette without the need for external data multiplexing. This allows a replacement graphics board to remain downward compatible by utilizing the existing graphics circuitry often located on the motherboard.

The 24- and 16-bit true-color modes that are provided allow bits of color information to be transferred directly from the pixel port to the digital-to-analog converters (DACs). Depending on which true-color mode is selected, an overlay function is provided using the remaining bits of the pixel bus. The 24-bit modes allow overlay with the eight remaining bits of the pixel bus, while the TARGA (5-5-5) 16-bit mode allows overlay with the one remaining bit of the divided pixel bus.

The TLC34076 has a 256-by-24 color-lookup table with triple, 8-bit video, D/A converters capable of directly driving a doubly terminated, 75-Ω line. Synchronization generation is incorporated on the green output channel. HSYNC and VSYNC are fed through the device and optionally inverted to indicate screen resolution to the monitor. A palette page register provides the additional bits of palette address when 1-, 2-, or 4-bit planes are used. This allows the screen colors to be changed with only one MPU write cycle.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TIGA is a trademark of Texas Instruments Incorporated.

TLC34076

VIDEO INTERFACE PALETTE

XLAS076 – MAY 1995

description (continued)

Clocking is provided through one of four or five inputs (three TTL- and either one ECL- or two TTL-compatible) and is software selectable. The video and shift-clock outputs provide a software-selected divide ratio of the chosen clock input.

The TLC34076 can be connected directly to the serial port of VRAM devices, eliminating the need for any discrete logic. Support for split shift-register transfers is also provided.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE	
			PLASTIC CHIP CARRIER (FN)	GRID ARRAY (GA)
0°C to 70°C	85 MHz	8 Bits	TLC34076-85FN	–
	110 MHz	8 Bits	TLC34076-110FN	–
	135 MHz	8 Bits	TLC34076-135FN	–
	170 MHz	8 Bits	TLC34076-170FN	–
–55°C to 125°C	135 MHz	8 Bits	–	TLC34076-135MGA

function block diagram

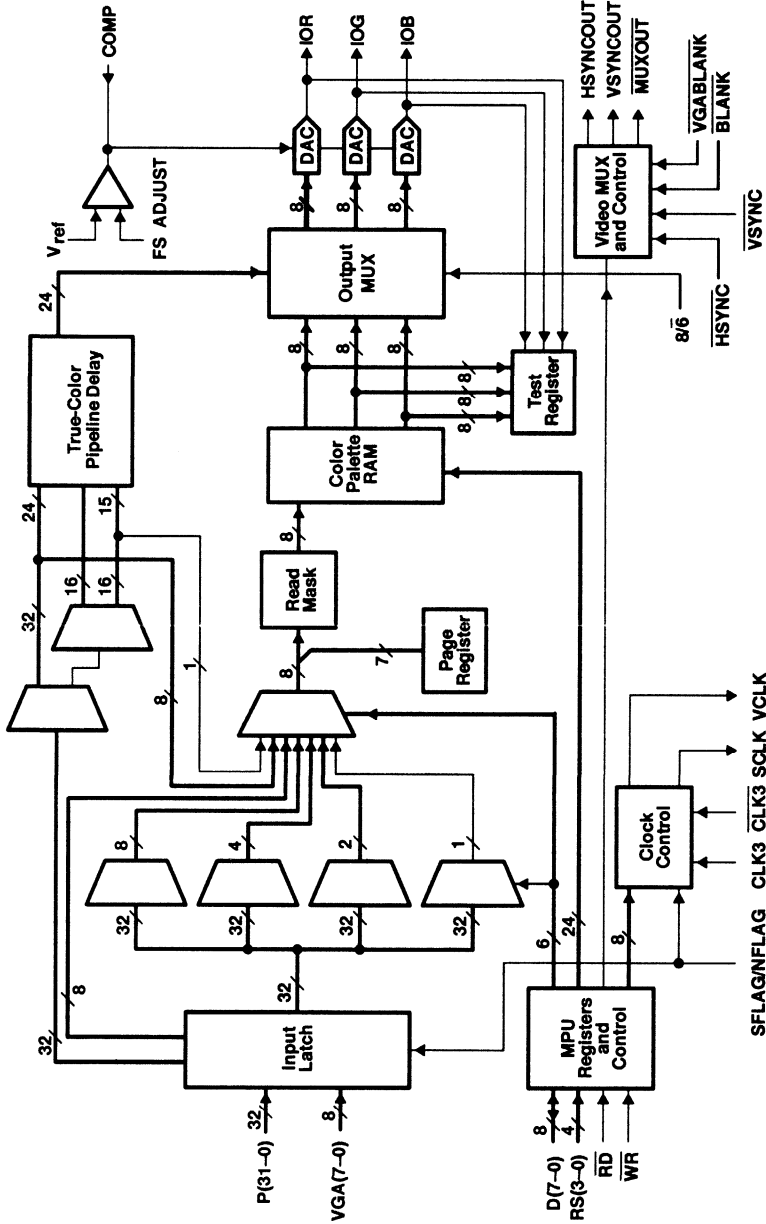


Figure 1. Functional Block Diagram

TLC34077 VIDEO INTERFACE PALETTE

XLAS045 - APRIL 1995

- Versatile Multiplexing Interface Allows Lower Pixel Bus Rate
- High Level of Integration Provides Lower System Cost and Complexity
- Direct VGA Pass-Through Capability
- True-Color (Direct Addressing) Modes Support Various 24- and 16-Bit Formats
- XGA™-Format Compatible (5-6-5)
- TARGA™-Format Compatible (5-5-5)
- Directly Interfaces to Most Graphics Processors
- Triple 8-Bit D/A Converters
- 110- and 135-MHz Versions
- 256-Word Color Palette RAM
- On-Chip Voltage Reference
- RS-343A-Compatible Outputs
- TTL-Compatible Inputs
- Standard MPU Interface
- Pixel Word Mask
- On-Chip Clock Selection
- Software Downward-Compatible With INMOS MSG176/8 and BrookTree™ Bt476/8 Color Palettes
- TIGA™ Software-Standard Compatible
- CMOS Technology
- Data Manual Available†

description

The TLC34077 video interface palette (VIP) is designed to provide lower system cost with a higher level of integration by incorporating all the high-speed timing, synchronization, and multiplexing logic usually associated with graphics systems into one device, thus greatly reducing chip count. Since all high-speed signals (excluding the clock source) are contained on-chip, RF noise considerations are simplified. Maximum flexibility is provided through the pixel multiplexing scheme, which allows for 32-, 16-, and 8-bit pixel buses to be accommodated without any circuit modification. The TLC34077 is software compatible with the MSG176/8 and Brooktree Bt476/8 color palettes.

The TLC34077 VIP is terminal-for-terminal compatible with the TLC34076 VIP, but with a reduced feature set optimized for cost-sensitive, high-performance, PC graphics applications. The TLC34077 is compatible with a variety of graphics processors, including the ATI 68800 *mach 32* series of graphics accelerators.

The TLC34077 features a separate VGA bus that allows data from the feature connector of most VGA-supported personal computers to be fed directly into the palette without the need for external data multiplexing. This allows a replacement graphics board to remain downward compatible by utilizing the existing graphics circuitry often located on the motherboard.

The 24- and 16-bit true-color modes that are provided allow bits of color information to be transferred directly from the pixel port to the DACs.

The TLC34077 has a 256-by-24 color-lookup table with triple, 8-bit video, D/A converters capable of directly driving a doubly terminated, 75-Ω line. Synchronization generation is incorporated on the green output channel.

Clocking is provided through one of two TTL-compatible inputs and is software selectable. The video clock output provides a software-selected divide ratio of the chosen clock input.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			PLASTIC CHIP CARRIER (FN)
0°C to 70°C	110 MHz	8 Bits	TLC34077-110FN
	135 MHz	8 Bits	TLC34077-135FN

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TIGA is a trademark of Texas Instruments Incorporated.

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TLC34077 VIDEO INTERFACE PALETTE

XLAS045 - APRIL 1995

functional block diagram

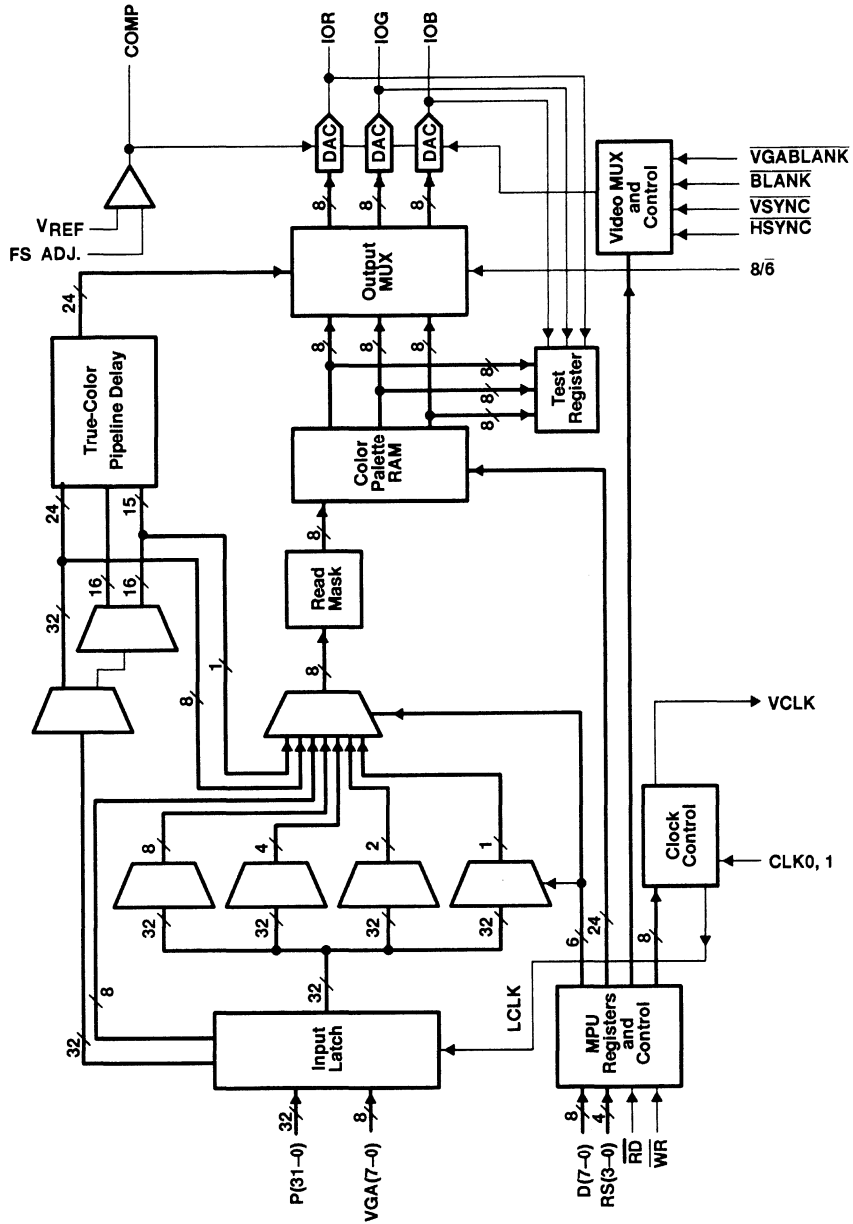


Figure 1. Functional Block Diagram

TVP2002 CLOCK DRIVER

XLAS083 – MAY 1995

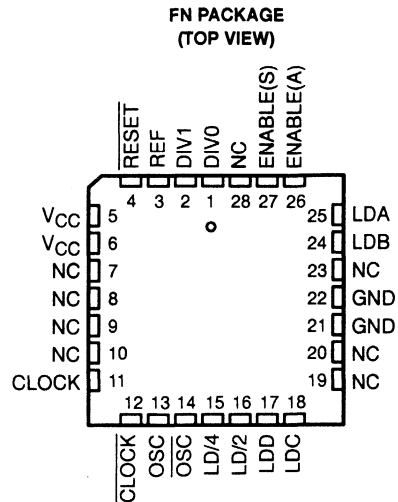
- 135-MHz Operation
- Differential ECL Clock Generation
- Divide by 3, 4, 5, or 8 of the Clock
- Divide by 2 and 4 of the Load
- Resets Pipeline Delay of the TLC34058
- 1.235-V Voltage Reference Output
- 5-V Single Power-Supply Operation
- 28-Pin PLCC (FN) Package
- Low Power Consumption . . . 400 mW Max
- Designed to Be Interchangeable With Brooktree™ Bt438
- Data Sheet Available†

description

The TVP2002 is a clock driver for the Texas Instruments TLC34058 and functionally equivalent color palettes. It interfaces to a 10 KH-ECL oscillator operating from a single 5-V supply to the TLC34058, generating the necessary clock and control signals.

The clock output may be divided by 3, 4, 5, or 8 to generate the load signal. The load signal is also divided by 2 and 4 for clocking video timing logic, for example. A second load signal may be synchronously or asynchronously controlled to enable starting and stopping of the VRAM clock.

The TVP2002 also optionally configures the pipeline delay of the TLC34058 to a fixed-pipeline delay. An on-chip 1.235-V reference is provided and may be used to provide the reference voltage for the color palette.



AVAILABLE OPTIONS

T _A	PACKAGE
	PLASTIC CHIP CARRIER (FN)
0°C to 70°C	TVP2002FN

† For the complete data sheet, refer to the Graphics and Imaging Data Book (SLAD002). Brooktree is a trademark of Brooktree Corporation.

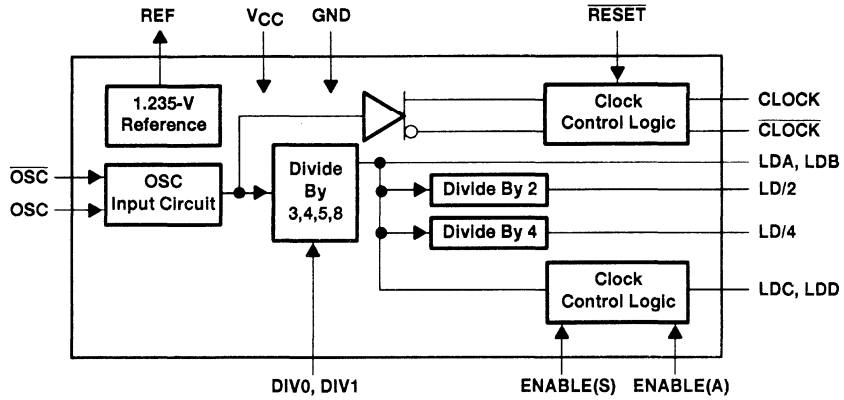
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TVP2002 CLOCK DRIVER

XLAS083 - MAY 1995

functional block diagram



- **Second-Generation Video Interface Palette**
- **Supports System Resolutions of:**
 - 1600 × 1280 × 1, 2, 4, 8, 16 Bits/Pixel at 60-Hz Refresh Rate
 - 1280 × 1024 × 1, 2, 4, 8, 16 Bits/Pixel at 60-Hz and 72-Hz Refresh Rates
 - 1024 × 768 × 1, 2, 4, 8, 16, 24 Bits/Pixel at 60-Hz and 72-Hz Refresh Rates
 - Lower Resolutions
- **Direct-Color Modes:**
 - 24-Bit/Pixel with 8-Bit Overlay
 - 16-Bit/Pixel (5, 6, 5) XGA™ Configuration
 - 16-Bit/Pixel (6, 6, 4) Configuration
 - 15-Bit/Pixel With 1-Bit Overlay (5, 5, 5, 1) TARGA™ Configuration
 - 12-Bit/Pixel With 4-Bit Overlay (4, 4, 4, 4)
- **True-Color Modes:**
 - 24-Bit/Pixel With Gamma Correction
 - 16-Bit/Pixel (5, 6, 5) XGA Configuration With Gamma Correction
 - 16-Bit/Pixel (6, 6, 4) Configuration with Gamma Correction
 - 15-Bit/Pixel (5, 5, 5) TARGA Configuration With Gamma Correction
 - 12-Bit/Pixel (4, 4, 4) With Gamma Correction
- **RCLK/SCLK/LCLK Data Latching Allows Flexible Control of VRAM Timing**
- **Direct Interfacing to Video RAM**
- **Supports Split Shift-Register Transfers**
- **64-Bit Wide Pixel Bus**
- **On-Chip Hardware Cursor:**
 - 64 × 64 × 2 Cursor (XGA Functionally Compatible)
 - Full-Window Crosshair
 - Dual-Cursor Mode
- **85-, 110-, 135- and 170-MHz Versions**
- **Supports Overscan For Creation of Custom Screen Borders**
- **Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats**
- **Windowed Overlay, VGA Capability**
- **Color-Keyed Switching of Direct Color and Overlay**
- **On-Chip Clock Selection**
- **Internal Frequency Doubler**
- **Triple 8-Bit D/A Converters**
- **Analog Output Comparators**
- **Triple 256 × 8 Color Palette RAMs**
- **RS-343A-Compatible Outputs**
- **Direct VGA Pass-Through Capability**
- **Palette-Page Register**
- **Horizontal Zooming Capability**
- **Software Downward Compatible With IMSG176/8 and Bt476/8**
- **Directly Interfaces to Graphics Processors**
- **CMOS Technology**
- **Data Manual Available†**

description

The TVP3010 palette is an advanced video interface palette (VIP) from Texas Instruments implemented in the EPIC™ 0.8-micron CMOS process. Maximum flexibility is provided by the pixel multiplexing scheme. The scheme accommodates 64-, 32-, 16-, 8-, and 4-bit pixel buses without any circuit modification. This enables the system to be easily reconfigured for varying amounts of available video RAM. The device supports selection of little- or big-endian data format for the pixel-bus/frame-buffer interface. Data can be split into 1-, 2-, 4-, or 8-bit planes for pseudo-color mode or split into 12-, 16- or 24-bit true-color and direct-color modes. For the 24-bit direct color modes, an 8-bit overlay plane is available. The 16-bit direct- and true-color modes can be configured to IBM™ XGA (5, 6, 5), TARGA (5, 5, 5, 1), or (6, 6, 4) as another existing format. An additional 12-bit mode (4, 4, 4, 4) is supported with 4 bits for each color and overlay. An on-chip, IBM XGA-compatible hardware cursor is incorporated so that further increases in graphics system performance are possible. The device is also software compatible with the IMSG176/8 and Bt476/8 color palettes.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TVP3010 VIDEO INTERFACE PALETTE

XLAS082 – MAY 1995

description (continued)

An internal frequency doubler is incorporated, allowing convenient and cost-effective clock source alternatives to be utilized. An auxiliary windowing function and a pixel-port-select function are provided so that overlay or VGA graphics can be displayed on top of direct color inside or outside a specified auxiliary window. Color-keyed switching of direct color and overlay is also supported.

Clocking is provided through one of five TTL inputs, CLK0–CLK4, and is software selectable. Additionally, CLK1/CLK2 and CLK3/CLK4 can be selected as differential ECL clock sources. The video, shift clock, and reference clock outputs provide a software-selected divide ratio of the chosen clock input. The reference clock can optionally be provided as an output on CLK3, and a data latch clock can optionally be input on CLK4.

The TVP3010 has three 256-by-8 color lookup tables with triple, 8-bit video, digital-to-analog converters (DACs) capable of directly driving a doubly terminated 75-Ω line. The lookup tables are designed with a dual-ported RAM architecture that enables ultra-high speed operation. Sync generation is incorporated on the green output channel. Horizontal sync and vertical sync are fed through the device and optionally inverted to indicate screen resolution to the monitor. A palette-page register provides the additional bits of palette address when 1-, 2-, or 4-bit planes are used. This allows the screen colors to be changed with only one microprocessor interface unit (MPU) write cycle.

The device features a separate VGA bus that allows data from the feature connector of most VGA-supported personal computers to be fed directly into the palette without the need for external data multiplexing. This allows a replacement graphics board to remain downward compatible by utilizing the existing graphics circuitry often located on the motherboard.

The TVP3010 VIP is highly system integrated. It can be connected to the serial port of VRAM devices without external buffer logic and connected to many graphics engines directly. The split shift-register transfer function, which is supported by VRAM, is also supported by the TVP3010.

The system-integration concept is carried to manufacturing test and field diagnosis. To support these, several highly integrated test functions have been designed to enable simplified testing of the palette, the graphics board, and the graphics system.

The 32-bit TVP3010 is terminal compatible with the TLC3407X VIP, allowing convenient performance upgrades when using devices in the TI Video Interface Palette family.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE	
			PLASTIC CHIP CARRIER (FN)	GRID ARRAY (GA)
0°C to 70°C	85 MHz	8 Bits	TVP3010-85FN	–
	110 MHz	8 Bits	TVP3010-110FN	–
	135 MHz	8 Bits	TVP3010-135FN	–
	170 MHz	8 Bits	TVP3010-170FN	–
–55°C to 125°C	135 MHz	8 Bits	–	TVP3010-135MGA

functional block diagram

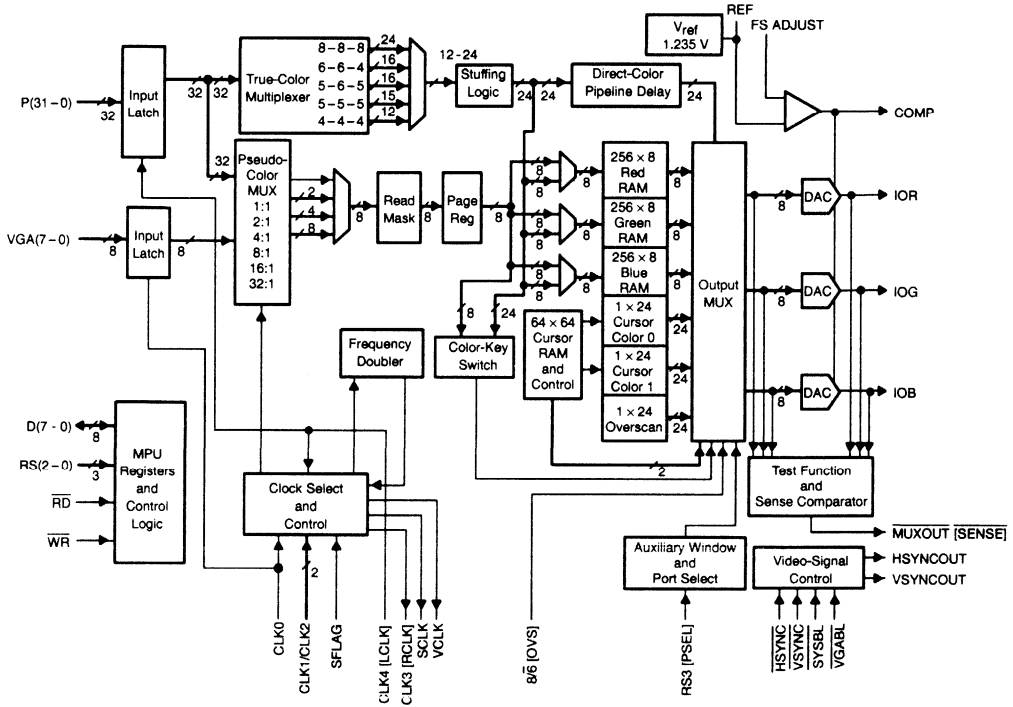


Figure 1. Functional Block Diagram

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- **Second-Generation Video Interface Palette**
- **Supports System Resolutions of:**
 - 1600 × 1280 × 1, 2, 4, 8, 16, 24 Bits/Pixel at 60-Hz and 72-Hz Refresh Rate
 - 1280 × 1024 × 1, 2, 4, 8, 16, 24 Bits/Pixel at 60-Hz and 72-Hz Refresh Rate
 - 1024 × 768 × 1, 2, 4, 8, 16, 24 Bits/Pixel at 60-Hz and 72-Hz Refresh Rate
 - And lower resolutions
- **Direct-Color Modes:**
 - 24-Bit/Pixel With 8-Bit Overlay
 - 16-Bit/Pixel (5, 6, 5) XGA® Configuration
 - 16-Bit/Pixel (6, 6, 4) Configuration
 - 15-Bit/Pixel With 1-Bit Overlay (5, 5, 5, 1) TARGA Configuration
 - 12-Bit/Pixel With 4-Bit Overlay (4, 4, 4, 4)
- **True-Color Modes:**
 - 24-Bit/Pixel With Gamma Correction
 - 16-Bit/Pixel (5, 6, 5) XGA Configuration With Gamma Correction
 - 16-Bit/Pixel (6, 6, 4) Configuration With Gamma Correction
 - 15-Bit/Pixel (5, 5, 5) TARGA® Configuration With Gamma Correction
 - 12-Bit/Pixel (4, 4, 4) With Gamma Correction
- **RCLK/SCLK/LCLK Data Latching Allows Flexible Control of VRAM Timing**
- **Direct Interfacing to Video RAM**
- **Supports Split Shift-Register Transfers**
- **64-Bit-Wide Pixel Bus**
- **On-Chip Hardware Cursor:**
 - 64 × 64 × 2 Cursor (XGA Functionally Compatible)
 - Full-Window Crosshair
 - Dual-Cursor Mode
- **135-, 170-, and 200-MHz Versions**
- **Supports Overscan for Creation of Custom Screen Borders**
- **Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats**
- **Windowed Overlay, VGA Capability**
- **Color-Keyed Switching of Direct Color and Overlay**
- **On-Chip Clock Selection**
- **Internal Frequency Doubler**
- **Triple 8-Bit D/A Converters**
- **Analog-Output Comparators**
- **Triple 256 × 8 Color Palette RAMs**
- **RS-343A-Compatible Outputs**
- **Direct VGA Pass-Through Capability**
- **Palette-Page Register**
- **Horizontal Zooming Capability**
- **Software Downward Compatible With IMSG176/8 and Bt476/8**
- **Directly Interfaces to Graphics Processors**
- **CMOS Technology**
- **Data Manual Available†**

description

The TVP3020 viewpoint palette is an advanced video interface palette (VIP) from Texas Instruments implemented in EPIC™ 0.8-micron CMOS process. Maximum flexibility is provided by the pixel multiplexing scheme. The scheme accommodates 64-, 32-, 16-, 8-, and 4-bit pixel buses without any circuit modification. This enables the system to be easily reconfigured for varying amounts of available video RAM. The device supports selection of little- or big-endian data format for the pixel-bus-frame buffer interface. Data can be split into 1-, 2-, 4-, or 8-bit planes for pseudo-color mode or split into 12-, 16- or 24-bit true-color and direct-color modes. For the 24-bit direct color modes, an 8-bit overlay plane is available. The 16-bit direct- and true-color modes can be configured to IBM XGA® (5, 6, 5), TARGA® (5, 5, 5, 1), or (6, 6, 4) as another existing format. An additional 12-bit mode (4, 4, 4, 4) is supported with 4 bits for each color and overlay. An on-chip, IBM XGA-compatible hardware cursor is incorporated so that further increases in graphics system performance are possible. The device is also software compatible with the IMSG176/8 and Bt476/8 color palettes.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TARGA is a trademark of Truevision Incorporated.

TVP3020 VIDEO INTERFACE PALETTE

XLAS080A – MAY 1995

description (continued)

An internal frequency doubler is incorporated, allowing convenient and cost-effective clock source alternatives to be utilized.

An auxiliary windowing function and a pixel-port-select function are provided so that overlay or VGA graphics can be displayed on top of direct color inside or outside a specified auxiliary window. Color-keyed switching of direct color and overlay is also supported.

Clocking is provided through one of three inputs (two TTL- and one ECL/TTL-compatible) and is software selectable. The video clock, shift clock, and reference clock outputs provide a software-selected divide ratio of the chosen clock input.

The TVP3020 has three 256-by-8 color lookup tables with triple, 8-bit video, digital-to-analog converters (DACs) capable of directly driving a doubly terminated, 75-Ω line. The lookup tables are designed with a dual-ported RAM architecture that enables ultra-high speed operation. Sync generation is incorporated on the green output channel. Horizontal sync (HSYNC) and vertical sync (VSYNC) are fed through the device and optionally inverted to indicate screen resolution to the monitor. A palette-page register provides the additional bits of the palette address when 1-, 2-, or 4-bit planes are used. This allows the screen colors to be changed with only one microprocessor interface unit (MPU) write cycle.

The device features a separate VGA bus that allows data from the feature connector of most VGA-supported personal computers to be fed directly into the palette without the need for external data multiplexing. This allows a replacement graphics board to remain downward compatible by utilizing the existing graphics circuitry often located on the motherboard.

The viewpoint VIP is highly system integrated. It can be connected to the serial port of VRAM devices without external buffer logic and connected to many graphics engines directly. The split shift-register transfer function, which is supported by VRAM, is also supported by the TVP3020.

The system-integration concept is carried to manufacturing test and field diagnosis. To support these, several highly integrated test functions have been designed to enable simplified testing of the palette, the graphics board, and the graphics system.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE	
			FLAT PACK (MDN)	FLAT PACK (PCE)
0°C to 70°C	135 MHz	8 Bits	–	TVP3020–135PCE
	170 MHz	8 Bits	–	TVP3020–170PCE
	200 MHz	8 Bits	TVP3020–200MDN	–

TVP3020 VIDEO INTERFACE PALETTE

XLAS080A - MAY 1995

functional block diagram

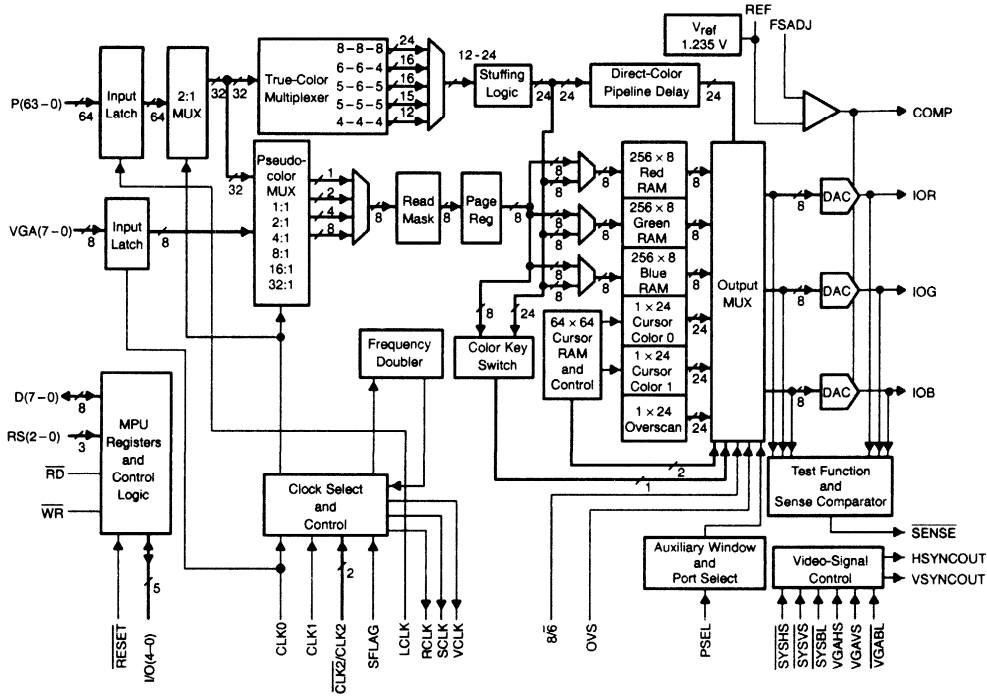


Figure 1. Functional Block Diagram

- 64-Bit Wide Pixel Bus
- Compatible With the S3 Vision964™ and 86C928
- Brooktree BT485 Register Map Emulation
- Supports System Resolutions of:
 - 1600 × 1280 × 1-, 2-, 4-, 8-, 16-, 24-Bits/Pixel at 60-Hz, 72, and 76-Hz Refresh Rate
 - 1536 × 1152 × 1-, 2-, 4-, 8-, 16-, 24-Bits/Pixel at 60-Hz and 72-Hz and Higher Refresh Rates
 - 1280 × 1024 × 1-, 2-, 4-, 8-, 16-, 24-Bits/Pixel at 60-Hz and 72-Hz and Higher Refresh Rates
 - 1024 × 768 × 1-, 2-, 4-, 8-, 16-, 24-Bits/Pixel at 60-Hz and 72-Hz and Higher Refresh Rates
 - And lower resolutions
- Direct-Color Modes:
 - 24-Bit/Pixel with 8-Bit Overlay
 - 16-Bit/Pixel (5, 6, 5) XGA™ Configuration
 - 16-Bit/Pixel (6, 6, 4) Configuration
 - 15-Bit/Pixel With 1-Bit Overlay (5, 5, 5, 1) TARGA™ Configuration
 - 12-Bit/Pixel With 4-Bit Overlay (4, 4, 4, 4)
- True-Color Modes:
 - 24-Bit/Pixel With Gamma Correction
 - 16-Bit/Pixel (5, 6, 5) XGA Configuration With Gamma Correction
 - 16-Bit/Pixel (6, 6, 4) Configuration with Gamma Correction
 - 15-Bit/Pixel (5, 5, 5) TARGA Configuration With Gamma Correction
 - 12-Bit/Pixel (4, 4, 4) With Gamma Correction
- RCLK/SCLK/LCLK Data Latching Allows Flexible Control of VRAM Timing
- Direct Interfacing to Video RAM
- Supports Split Shift-Register Transfers
- 135-, 170-, and 200-MHz Versions
- Integrated Pixel Clock and Memory Clocks Phase-Locked Loops (PLL)
- On-Chip Hardware Cursor:
 - 64 × 64 × 2 Cursor (XGA Functionally Compatible)
 - Full-Window Crosshair
 - Dual-Cursor Mode
- On-Chip Clock Selection
- Supports Overscan For Creation of Custom Screen Borders
- Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats
- Windowed Overlay, VGA Capability
- Color-Keyed Switching of Direct Color and Overlay
- Horizontal Zooming Capability
- Triple 8-Bit D/A Converters
- Analog-Output Comparators
- Triple 256 × 8 Color Palette RAMs
- RS-343A-Compatible Outputs
- Direct VGA Pass-Through Capability
- Palette-Page Register
- Software Downward Compatible With IMSG176/8 and Bt476/8
- CMOS Technology
- Data Manual Available†

description

The TVP3025 is an advanced video interface palette (VIP) from Texas Instruments implemented in EPIC™ 0.8-micron CMOS process. The TVP3025 is a superset of the 64-bit TVP3020 VIP with the addition of Brooktree Bt485 register map emulation and frequency synthesis phase-locked loops (PLLs). The BT485 register emulation mode allows the device to be software compatible with many graphics controllers, including the S3 Vision964™ and 86C928 VRAM-based graphics accelerators. This new 64-bit device provides an effective migration path from lower performance graphics systems which utilize previous generation 32-bit color palettes.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TARGA is a trademark of Truevision Incorporated.
Vision964 is a trademark of S3 Corporation.

TVP3025 VIDEO INTERFACE PALETTE

XLAS090 – MAY 1995

description (continued)

The TVP3025 is a functional superset of the TVP3020 and features the same 64-bit programmable pixel bus interface. Data can be split into 1-, 2-, 4-, or 8-bit planes for pseudo-color mode or split into 12-, 16- or 24-bit true-color and direct-color modes. For the 24-bit direct color modes, an 8-bit overlay plane is available. The 16-bit direct- and true-color modes can be configured to IBM XGA (5, 6, 5), TARGA (5, 5, 5, 1), or (6, 6, 4) as another existing format.

An additional 12-bit mode (4, 4, 4, 4) is supported with 4 bits for each color and overlay. All color modes support selection of little or big endian data format for the pixel bus. Additionally, the device is also software compatible with the IM5G176/8 and Bt476/8 color palettes.

Clocking is provided through one of four inputs (two TTL- and one ECL/TTL-compatible) or two crystal oscillator inputs, and is software selectable. The video, shift clock, and reference clock outputs provide a software-selected divide ratio of the chosen clock input. Two fully programmable PLLs for pixel clock and memory clock functions are provided, as well as a simple frequency doubler for dramatic improvements in graphics system cost and integration. A third loop clock PLL is incorporated making pixel data latch timing much simpler than with other existing color palettes.

Like the TVP3020, the TVP3025 also integrates a complete, IBM XGA-compatible hardware cursor on chip, making significant graphics performance enhancements possible. Additionally, auxiliary windowing, port-select and color-keyed switching functions are provided, giving the user several efficient means of producing graphical overlays on direct-color backgrounds.

The TVP3025 has three 256-by-8 color lookup tables with triple, 8-bit video, digital-to-analog converters (DACs) capable of directly driving a doubly terminated, 75-Ω line. The lookup tables are designed with a dual-ported RAM architecture that enables ultra-high speed operation. Sync generation is incorporated on the green output channel. Horizontal sync (HSYNC) and vertical sync (VSYNC) are fed through the device and optionally inverted to indicate screen resolution to the monitor. A palette-page register is available to provide the additional bits of palette address when 1-, 2-, or 4-bit planes are used. This allows the screen colors to be changed with only one microprocessor interface unit (MPU) write cycle.

The device features a separate VGA bus that allows data from the feature connector of most VGA-supported personal computers to be fed directly into the palette without the need for external data multiplexing. The separate bus also is useful in graphics accelerator applications, allowing efficient VGA and text mode support.

The TVP3025 is highly system integrated. It can be connected to the serial port of VRAM devices without external buffer logic and connected to many graphics engines directly. It also supports the split shift-register transfer function, which is common to many industry standard VRAM devices.

The system-integration concept is carried to manufacturing test and field diagnosis. To support these, several highly integrated test functions have been designed to enable simplified testing of the palette and the entire graphics system.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE	
			FLAT PACK (MDN)	FLAT PACK (PCE)
0°C to 70°C	135 MHz	8 Bits	–	TVP3025–135PCE
	170 MHz	8 Bits	–	TVP3025–170PCE
	200 MHz	8 Bits	TVP3025–200MDN	–

functional block diagram

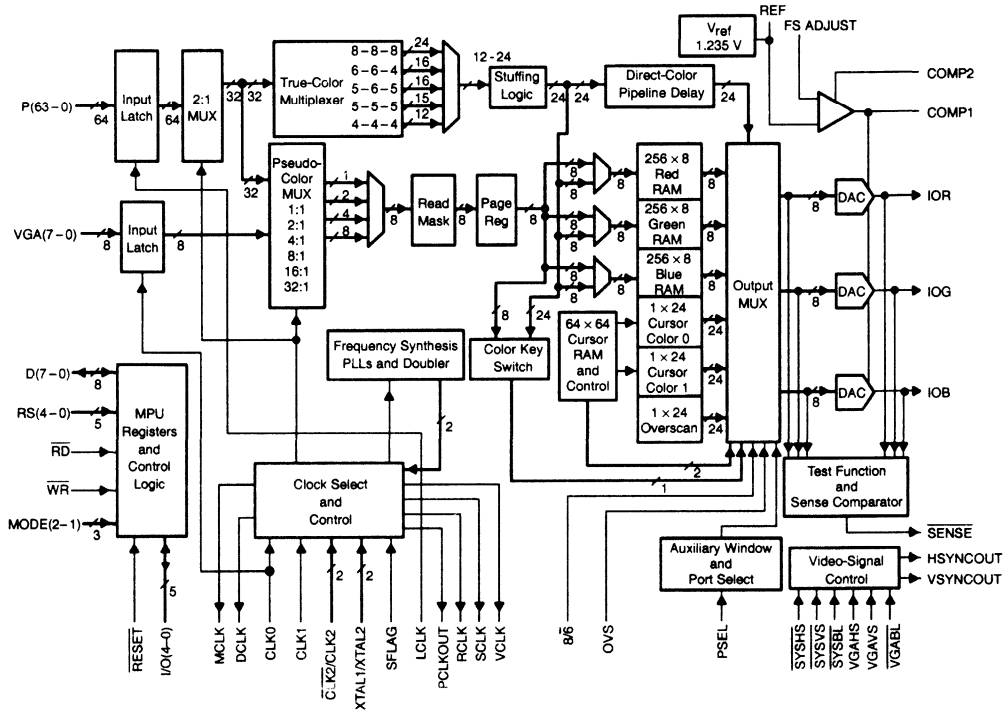


Figure 1. Functional Block Diagram

- Supports System Resolutions up to 1600 × 1280 at 76-Hz Refresh Rate
- Supports Color Depths of 4-, 8-, 16-, 24-, and 32-Bit/Pixel
- Versatile Direct-Color Modes:
 - 24-Bit/Pixel with 8-Bit Overlay (O, R, G, B)
 - 24-Bit/Pixel (R, G, B)
 - 16-Bit/Pixel (5, 6, 5) XGA™ Configuration
 - 16-Bit/Pixel (6, 6, 4) Configuration
 - 15-Bit/Pixel With 1-Bit Overlay (1, 5, 5, 5) TARGA™ Configuration
 - 12-Bit/Pixel With 4-Bit Overlay (4, 4, 4, 4)
- True-Color Gamma Correction
- Supports Packed Pixel Formats for 24-Bit/Pixel Using a 32- or 64-Bit/Pixel Bus
- 50% Duty Cycle Reference Clock for Higher Screen Refresh Rates in Packed-24 Modes
- Programmable Frequency Synthesis Phase-Locked Loops (PLL) for Dot Clock and Memory Clock
- Loop Clock PLL Compensates for System Delay and Ensures Reliable Data Latching
- Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats
- 135-, 175-, and 220-MHz Versions
- On-Chip Hardware Cursor, 64 × 64 × 2 Cursor (XGA and X-Window™ Functionally Compatible)
- Direct Interfacing to Video RAM
- Supports Overscan For Creation of Custom Screen Borders
- Color-Keyed Switching of Direct Color and and True Color or Overlay
- Hardware Port Select Switching Between Direct Color and True Color or Overlay
- Triple 8-Bit D/A Converters
- Analog-Output Comparators for Monitor Detection
- RS-343A-Compatible Outputs
- Direct VGA Pass-Through Capability
- Palette-Page Register
- Horizontal Zooming Capability
- CMOS Technology
- Data Manual Available†

description

The TVP3026 is an advanced video interface palette (VIP) from Texas Instruments implemented in EPIC™ 0.8-micron CMOS process. The TVP3026 is a 64-bit VIP that supports packed-24 modes enabling 24-bit true color and high resolution at the same time without excessive amounts of frame buffer memory. For example, a 24-bit true color display with 1280 x 1024 resolution may be packed into 4 megabytes of VRAM. A PLL-generated, 50% duty cycle reference clock is output in the packed-24 modes, maximizing VRAM cycle time and screen refresh rate.

The TVP3026 supports all of the pixel formats of the TVP3020 VIP. Data can be split into 4- or 8-bit planes for pseudo-color mode or split into 12-, 16- or 24-bit true-color and direct-color modes. For the 24-bit direct color modes, an 8-bit overlay plane is available. The 16-bit direct- and true-color modes can be configured to IBM™ XGA (5, 6, 5), TARGA (1, 5, 5, 5), or (6, 6, 4) as another existing format. An additional 12-bit mode (4, 4, 4, 4) is supported with 4 bits for each color and overlay. All color modes support selection of little- or big-endian data format for the pixel bus. Additionally, the device is also software compatible with the IM5G176/8 and Bt476/8 color palettes.

Two fully programmable PLLs for pixel clock and memory clock functions are provided, as well as a simple frequency doubler for dramatic improvements in graphics system cost and integration. A third loop clock PLL is incorporated, making pixel data latch timing much simpler than with other existing color palettes. In addition, four digital clock inputs (two TTL- and two ECL/TTL-compatible) can be used and are software selectable. The video clock provides a software-selected divide ratio of the chosen pixel clock. The shift clock output can be used directly as the VRAM shift clock. The reference clock output is driven by the loop clock PLL and provides a timing reference to the graphics accelerator.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TARGA is a trademark of Truevision Incorporated.

X-Window is a trademark of the Massachusetts Institute of Technology

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TVP3026

VIDEO INTERFACE PALETTE

XLAS098A - MAY 1995

description (continued)

Like the TVP3020, the TVP3026 also integrates a complete, IBM XGA-compatible hardware cursor on chip, making significant graphics performance enhancements possible. Additionally, hardware port select and color-keyed switching functions allow the user several options for producing graphical overlays on direct-color backgrounds.

The TVP3026 has three 256-by-8 color lookup tables with triple, 8-bit video, digital-to-analog converters (DACs) capable of directly driving a doubly terminated, 75- Ω line. The lookup tables are designed with a dual-port RAM architecture that enables ultra-high speed operation. Sync generation is incorporated on the green output channel. Horizontal sync (HSYNC) and vertical sync (VSYNC) are pipeline delayed through the device and optionally inverted to indicate screen resolution to the monitor. A palette-page register is available to select from multiple color maps in RAM when 4 bit planes are used. This allows the screen colors to be changed with only one microprocessor write cycle.

The device features a separate VGA bus that supports the integrated VGA modes in graphics accelerator applications, allowing efficient support for VGA graphics and text modes. The separate bus also is useful for accepting data from the feature connector of most VGA-supported personal computers, without the need for external data multiplexing.

The TVP3026 is highly system integrated. It can be connected to the serial port of VRAM devices without external buffer logic and connected to many graphics engines directly. It also supports the split shift-register transfer function, which is common to many industry standard VRAM devices.

The system-integration concept is even carried further to manufacturing test and field diagnosis. To support these, several highly integrated test functions have been designed to enable simplified testing of the palette and the entire graphics system.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			FLAT PACK (PCE)
0°C to 70°C	135 MHz	8 Bits	TVP3026-135PCE
	175 MHz	8 Bits	TVP3026-175PCE
	220 MHz	8 Bits	TVP3026-220PCE



functional block diagram

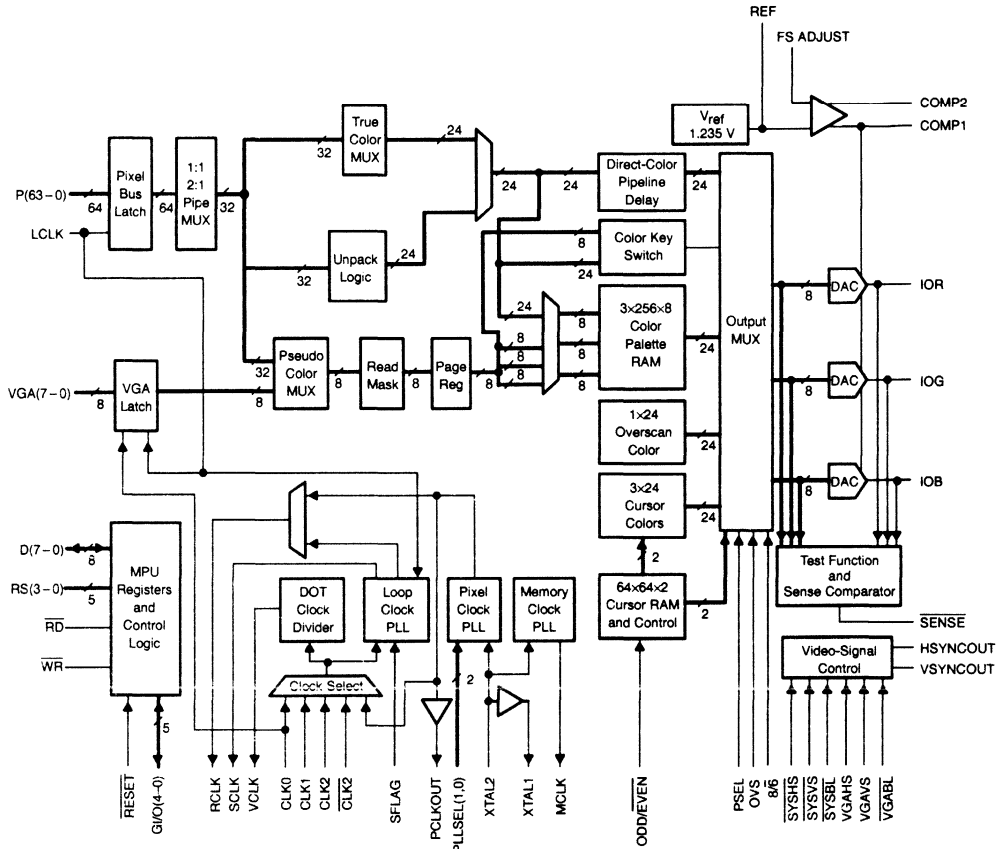


Figure 1. Functional Block Diagram

- Supports System Resolutions up to 1600 × 1280 at 76-Hz Refresh Rate
- Supports Color Depths of 4-, 8-, 16-, 24-, and 32-Bit/Pixel
- 64-Bit-Wide Pixel Bus
- Versatile Direct-Color Modes:
 - 24-Bit/Pixel with 8-Bit Overlay (O, R, G, B)
 - 24-Bit/Pixel (R, G, B)
 - 16-Bit/Pixel (5, 6, 5) XGA® Configuration
 - 16-Bit/Pixel (6, 6, 4) Configuration
 - 15-Bit/Pixel With 1-Bit Overlay (1, 5, 5, 5) TARGA® Configuration
 - 12-Bit/Pixel With 4-Bit Overlay (4, 4, 4, 4)
- True-Color Gamma Correction
- Supports Packed Pixel Formats for 24-Bit/Pixel Using a 32- or 64-Bit/Pixel Bus
- 50% Duty Cycle Reference Clock for Higher Screen Refresh Rates in Packed-24 Modes
- Programmable Frequency Synthesis Phase-Locked Loops (PLLs) for Dot Clock and Memory Clock
- Loop Clock PLL Compensates for System Delay and Ensures Reliable Data Latching
- Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats
- 135-, 175-, and 220-MHz Versions
- On-Chip Hardware Cursor, 64 × 64 × 2 Cursor (XGA and X-Windows Functionally Compatible)
- Direct Interfacing to Video RAM
- Supports Overscan For Creation of Custom Screen Borders
- Color-Keyed Switching of Direct Color and True Color or Overlay
- Hardware Port Select Switching Between Direct Color and True Color or Overlay
- Triple 8-Bit D/A Converters
- Analog-Output Comparators for Monitor Detection
- RS-343A-Compatible Outputs
- Direct VGA Pass-Through Capability
- Palette-Page Register
- Horizontal Zooming Capability
- CMOS Technology
- DOS OM-1 Compatible for 16-Bit Video with Graphics
- Additional VGA Clock Frequencies Pullups Added to Pixel Port Terminals
- Dot Clock Added to RCLK Output Multiplexor
- VESA Advanced-Feature Connector (VAFC) Baseline Connector Compatible
- Pixel Port Bank Switching
- Data Manual Available†

description

The TVP3027 is an advanced video interface palette (VIP) from Texas Instruments implemented in EPIC™ 0.8-micron CMOS process. The TVP3027 is an enhanced TVP3026. As such, it supports all modes and pixel formats of the TVP3026 VIP, including packed 24-bit true color with the phase-locked loop (PLL) generated, 50% duty cycle reference clock. In addition, the TVP3027 supports 16-bit video switching with graphics and VAFC baseline compatibility.

Like previous VIPs, data can be split into 4- or 8-bit planes for pseudo-color mode or split into 12-, 16- or 24-bit true-color and direct-color modes. For the 24-bit direct color modes, an 8-bit overlay plane is available. The 16-bit direct- and true-color modes can be configured to IBM XGA® (5, 6, 5), TARGA® (1, 5, 5, 5), or (6, 6, 4) as another existing format. An additional 12-bit mode (4, 4, 4, 4) is supported with 4 bits for each color and overlay. All color modes support selection of little or big endian data format for the pixel bus. Additionally, the device is also software compatible with the IMSG176/8 and Bt476/8 color palettes.

Two fully programmable PLLs for pixel clock and memory clock functions are provided for dramatic improvements in graphics system cost and integration. A third loop clock PLL is incorporated making pixel data latch timing much

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TVP3027 VIDEO INTERFACE PALETTE

XLAS106 – MAY 1995

description (continued)

simpler than with other existing color palettes. In addition, four digital clock inputs (two TTL- and two ECL/TTL-compatible) may be utilized and are software selectable. The video clock provides a software selected divide ratio of the chosen pixel clock. The shift clock output may be used directly as the VRAM shift clock. The reference clock output is driven by the loop clock PLL and provides a timing reference to the graphics accelerator.

Like the TVP3026, the TVP3027 integrates a complete, $64 \times 64 \times 2$ hardware cursor on chip, making significant graphics performance enhancements possible. Additionally, hardware port select and color keyed switching functions are provided, giving the user several efficient means of producing graphical overlays on direct-color backgrounds.

The TVP3027 has three 256-by-8 color lookup tables with triple, 8-bit video, digital-to-analog converters (DACs) capable of directly driving a doubly-terminated, $75\text{-}\Omega$ line. The lookup tables are designed with a dual-ported RAM architecture that enables ultra-high speed operation. Sync generation is incorporated on the green output channel. Horizontal sync (HSYNC) and vertical sync (VSYNC) are pipeline delayed through the device and optionally inverted to indicate screen resolution to the monitor. A palette-page register is available to select from multiple color maps in RAM when 4-bit planes are used. This allows the screen colors to be changed with only one microprocessor write cycle.

The device features a separate VGA bus which supports the integrated VGA modes in graphics accelerator applications, allowing efficient support for VGA graphics and text modes. The separate bus is also useful for accepting data from the feature connector of most VGA-supported personal computers, without the need for external data multiplexing.

The TVP3027 is highly system integrated. It can be connected to the serial port of video RAM (VRAM) devices without external buffer logic and connected to many graphics engines directly. It also supports the split shift-register transfer function, which is common to many industry standard VRAM devices.

The system-integration concept is even carried further to manufacturing test and field diagnosis. To support these, several highly integrated test functions have been designed to enable simplified testing of the palette and the entire graphics system.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			FLAT PACK (PCE)
0°C to 70°C	135 MHz	8 Bits	TVP3027-135PCE
	175 MHz	8 Bits	TVP3027-175PCE
	220 MHz	8 Bits	TVP3027-220PCE

PRODUCT
PREVIEW

functional block diagram

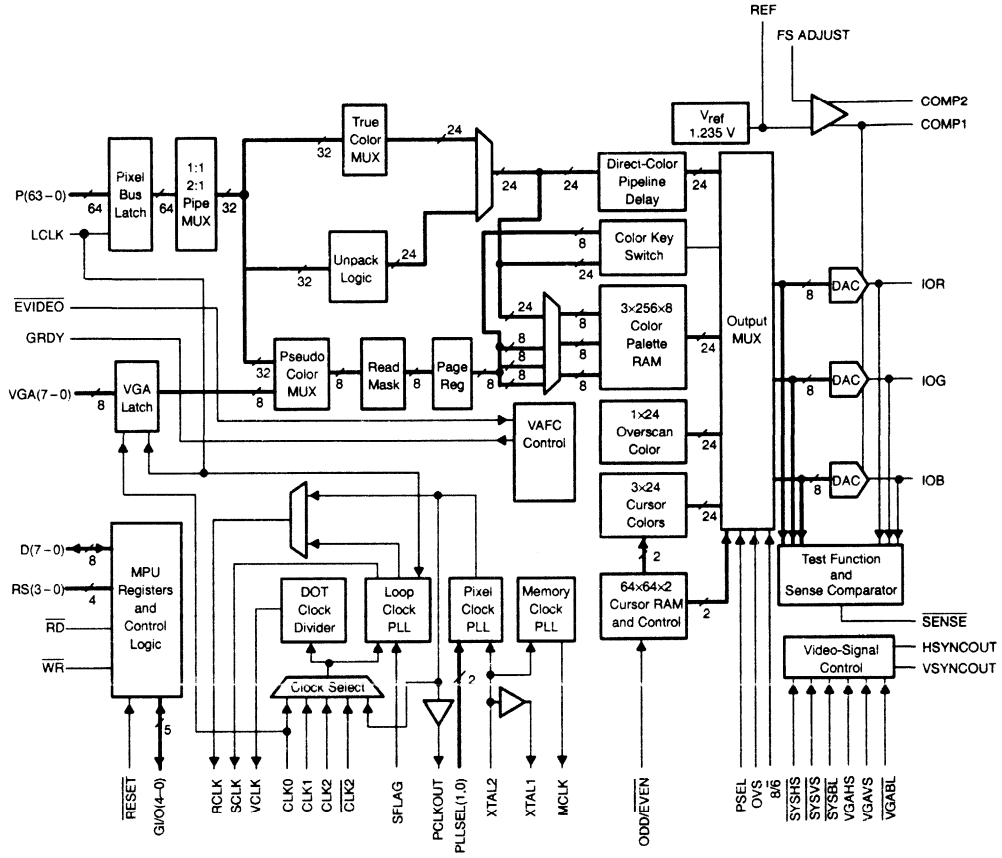


Figure 1. Functional Block Diagram

PRODUCT PREVIEW

- Supports System Resolutions up to 1600 × 1280 at 86-Hz Refresh Rate
- Supports Color Depths of 4-, 8-, 16-, 24-, and 32-Bit/Pixel, All at Maximum Resolution
- 128-Bit-Wide Pixel Bus
- Versatile Direct-Color Modes:
 - 24-Bit/Pixel With 8-Bit Overlay (O, R, G, B)
 - 24-Bit/Pixel (R, G, B)
 - 16-Bit/Pixel (5, 6, 5) XGA® Configuration
 - 16-Bit/Pixel (6, 6, 4) Configuration
 - 15-Bit/Pixel With 1-Bit Overlay (1, 5, 5, 5) TARGA® Configuration
 - 12-Bit/Pixel With 4-Bit Overlay (4, 4, 4, 4)
- True-Color Gamma Correction
- Supports Packed Pixel Formats for 24-Bit/Pixel Using a 32-, 64-, or 128-Bit/Pixel Bus
- 50% Duty Cycle Reference Clock for Higher Screen Refresh Rates in Packed-24 Modes
- Programmable Frequency Synthesis PLLs for Dot Clock and Memory Clock
- Loop Clock PLL Compensates for System Delay and Ensures Reliable Data Latching
- Versatile Pixel Bus Interface Supports Little- and Big-Endian Data Formats
- 175-, 220-, and 250-MHz Versions
- On-Chip Hardware Cursor, 64 × 64 × 2 Cursor (XGA and X-Windows Functionally Compatible)
- Byte Router Allows Use of R,G, or B Direct-Color Channels Individually
- Direct Interfacing to Video RAM
- Supports Overscan for Creation of Custom Screen Borders
- Color-Keyed Switching of Direct Color and and True Color or Overlay
- Triple 8-Bit D/A Converters
- Analog Output Comparators for Monitor Detection
- RS-343A-Compatible Outputs
- Direct VGA Pass-Through Capability
- Palette-Page Register
- Horizontal Zooming Capability
- CMOS Technology
- Data Manual Available†

description

The TVP3030 is an advanced video interface palette (VIP) from Texas Instruments implemented in EPIC™ 0.8-micron CMOS process. The TVP3030 is a 128-bit VIP that provides virtually all features of the 64-bit TVP3026. The TVP3030 doubles the pixel bus bandwidth, enabling 24-bit/pixel displays at resolutions up to 1600 × 1280 at a 76-Hz refresh rate. Also, 24-bit/pixel graphics at 1280 × 1024 resolution may be implemented at higher refresh rates with or without the use of pixel packing.

With the wider pixel bus comes additional 24-bit/pixel multiplexing modes: 4:1 [128-bit bus width for overlay, red, green, and blue (RGB)] and 5:1 (120-bit bus width for RGB). The byte router function allows pseudo-color or monochrome image data to be taken from the red, green, or blue color channels. This enables high performance 24-bit/pixel architectures organized as red, green, and blue memory banks to provide 8-bit/pixel modes as well.

The TVP3030 extends the packed-24 modes to include 16:3 (pixels:load clocks) using a 128-bit pixel bus width. This enables, for example, 24-bit/pixel graphics at 220 MHz pixel rate with only a 40 MHz VRAM serial output. With the 8:3 packed-24 mode (64-bit pixel bus width), a 24-bit/pixel display with 1280 × 1024 resolution may be packed into 4 megabytes of VRAM. A phase-locked loop (PLL) generated, 50 % duty cycle reference clock is output in the packed-24 modes, maximizing VRAM cycle time.

The TVP3030 supports all of the pixel formats of the TVP3026 VIP. Data can be split into 4- or 8-bit planes for pseudo-color mode or split into 12-, 16- or 24-bit true-color and direct-color modes. For the 24-bit direct color modes, an 8-bit overlay plane is available. The 16-bit direct- and true-color modes can be configured to IBM XGA® (5, 6, 5), TARGA® (5, 5, 5, 1), or (6, 6, 4) as another existing format. An additional 12-bit mode (4, 4, 4, 4) is supported with 4 bits for each color and overlay. All color modes support selection of little or big endian data format for the pixel bus. Additionally, the device is also software compatible with the IM5G176/8 and Bt476/8 color palettes.

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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TVP3030 VIDEO INTERFACE PALETTE

XLAS111 – MAY 1995

description (continued)

Two fully programmable PLLs for pixel clock and memory clock functions are provided for dramatic improvements in graphics system cost and integration. A third loop clock PLL is incorporated making pixel data latch timing much simpler than with other existing color palettes. In addition, an external digital clock input is provided for VGA modes. The reference clock output is driven by the loop clock PLL and provides a timing reference to the graphics accelerator. The shift clock output may be used directly as the VRAM shift clock.

Like the TVP3026, the TVP3030 also integrates a complete, IBM XGA-compatible hardware cursor on chip, making significant graphics performance enhancements possible. Additionally, color-keyed switching is provided, giving the user an efficient means of combining graphic overlays and direct-color images on-screen.

The TVP3030 has three 256-by-8 color lookup tables with triple, 8-bit video, digital-to-analog converters (DACs) capable of directly driving a doubly-terminated, 75-Ω line. The lookup tables are designed with a dual-ported RAM architecture that enables ultra-high speed operation.

The device features a separate VGA bus which supports the integrated VGA modes in graphics accelerator applications, allowing efficient support for VGA graphics and text modes. The separate bus is also useful for accepting data from the feature connector of most VGA-supported personal computers, without the need for external data multiplexing.

The TVP3030 is highly system integrated. It can be connected to the serial port of VRAM devices without external buffering and connected to many graphics engines directly. It also supports the split shift-register transfer operation, which is common to many industry standard VRAM devices. To aid in manufacturing test and field diagnosis, several highly integrated test functions have been designed to enable simplified testing of the palette and the entire graphics subsystem.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE	
			FLAT PACK (PPA)	FLAT PACK (MEP)
0°C to 70°C	175 MHz	8 Bits	TVP3030-175PPA	–
	220 MHz	8 Bits	TVP3030-220PPA	–
	250 MHz	8 Bits	–	TVP3030-250MEP

functional block diagram

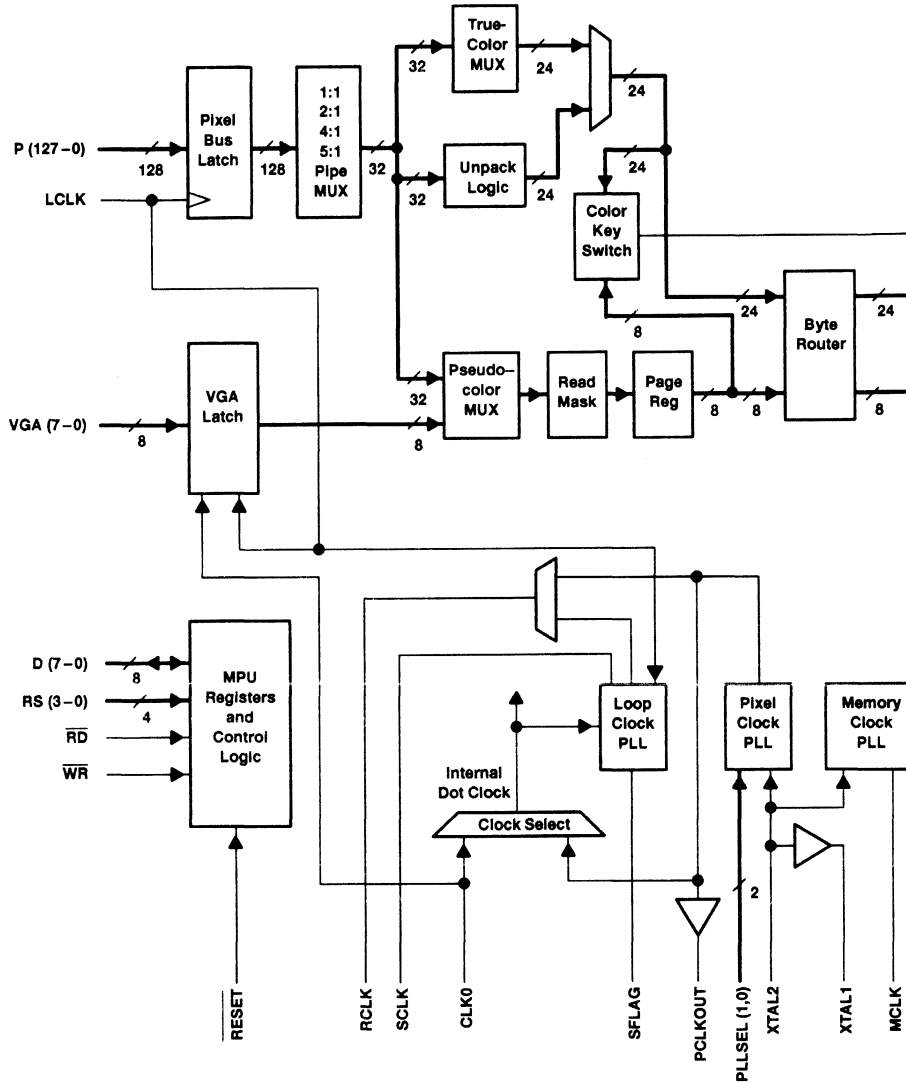


Figure 1. Functional Block Diagram

TVP3030 VIDEO INTERFACE PALETTE

XLAS111 – MAY 1995

functional block diagram (continued)

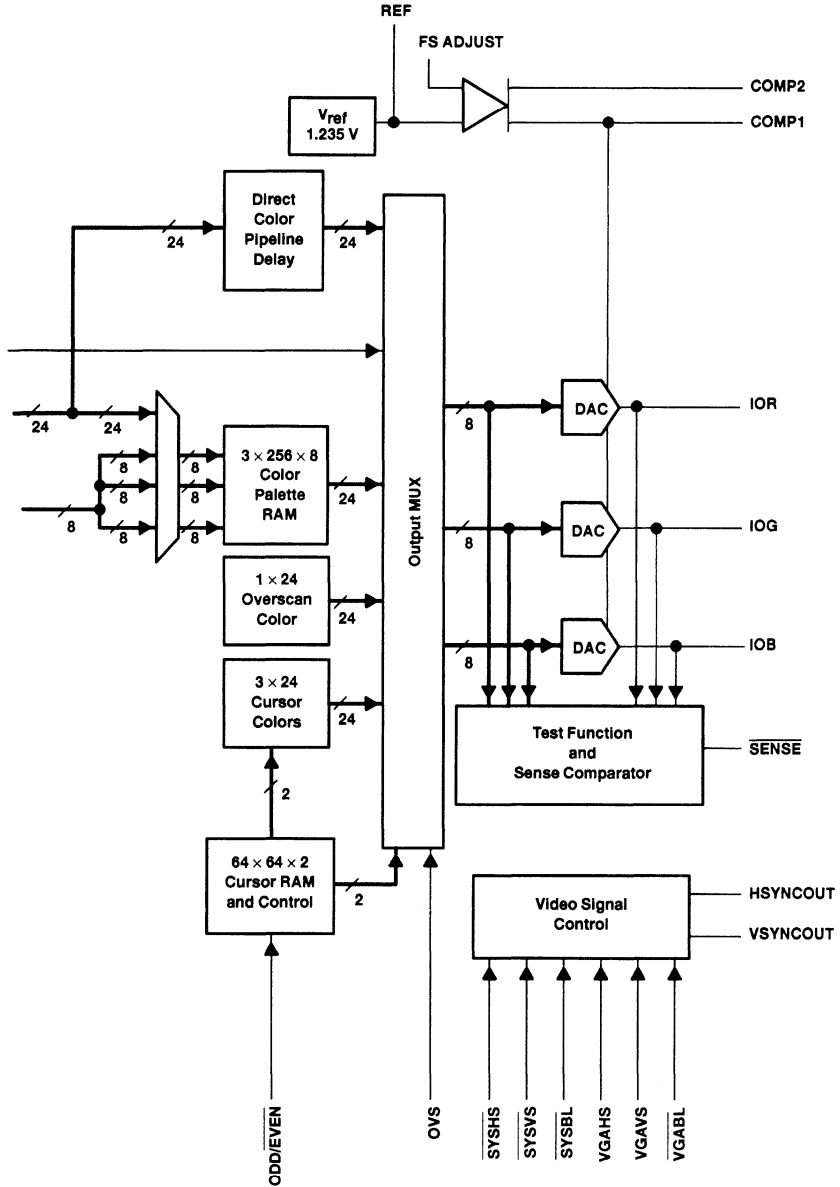


Figure 2. Functional Block Diagram

TVP3409

VIDEO INTERFACE PALETTE TRUE-COLOR CMOS RAMDAC

XLAS092 – MAY 1995

features

- Functionally Interchangeable With ATT20C409
- 170/135 MHz
 - 170 MHz 2:1 Multiplexer Rate for 8-Bit Pseudocolor Operation
 - 73 MHz True-Color Operation
- 16-Bit Pixel Port, Usable as 8-Bit Port
 - Compatible With ATT20C490 Using P(7-0)
 - Compatible With ATT20C498 Using P(15-0)
- 9 Software-Selectable Color Modes
 - 24-Bit Packed Pixels
 - 24-Bit 16-Bit True Color
 - 8-Bit Pseudocolor
- 2:1 and 1:1 Pixel Multiplexing
- Power Dissipation of 1.19 W at 135 MHz Typ
- Dual Programmable-Clock Synthesizers
 - Pixel Clock
 - Memory Clock
 - Reset to 28.322 MHz and 25.175 MHz VGA Frequencies
 - Strobe Input Latches Frequency Select Lines

- On-Chip PLL Clock Doubler
 - 85 MHz Input
 - 170 MHz Pixel Output
- 256 × 24 Color RAM
- Software Compatible With the AT&T ATT20C498/499/409
- 68-Terminal Plastic Leaded Chip Carrier (PLCC) Package
- Data Manual Available†

applications

- Screen Resolutions (noninterlaced)
 - 1600 × 1280, 8-Bit/Pixel, 60 Hz
 - 1280 × 1024, 16-Bit/Pixel, 60 Hz
 - 1024 × 768, 16-Bit/Pixel, 85 Hz
 - 1024 × 768, 24-Bit/Pixel, Packed, 70 Hz
 - 800 × 600, 24-Bit/Pixel, Unpacked, 72 Hz
- True-Color Desktop, PC Add-in Card
- X-Windows Terminals
- Green PCs

description

The TVP3409 is functionally interchangeable with the ATT20C409 RAMDAC.

The TVP3409 RAMDAC supports 8-bit multiplexed operation that can be input on 16-pixel terminals. The TVP3409 retains register compatibility with the ATT21C498 and ATT20C499 parts.

The TVP3409 features 24-bit, packed pixel modes that provide 24-bit graphics in a 3-Mbyte frame buffer at 1024 × 768 screen resolution. Dual clock synthesizers offer two programmable and two fixed frequencies in phase-locked loop (PLL) (A), and one programmable and three fixed frequencies in PLL (B). After reset the frequencies are:

PLL (A): 25.175, 28.322, 50, and 75 MHz

PLL (B): 30, 40, 50, and 60 MHz

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			CHIP CARRIER (FN)
0°C to 70°C	135 MHz	8 Bits	TVP3409-135CFN
	170 MHz	8 Bits	TVP3409-170CFN

† For the complete data manual, refer to the Graphics and Imaging Data Book (SLAD002).

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PRODUCT PREVIEW

TVP3409 VIDEO INTERFACE PALETTE TRUE-COLOR CMOS RAMDAC

XLAS092 - MAY 1995

functional block diagram

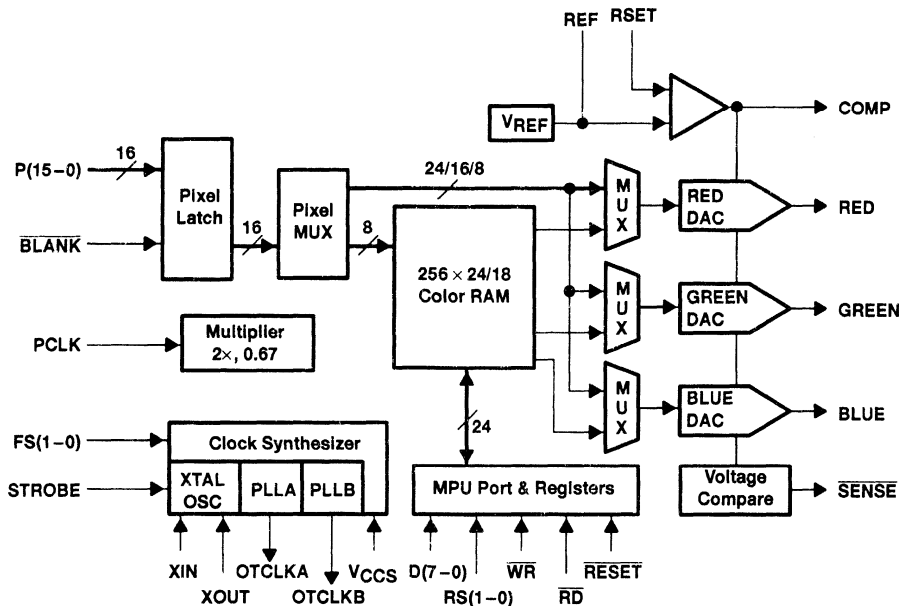


Figure 1. Functional Block Diagram

PRODUCT PREVIEW

- Fully Integrated Dual Clock Synthesizer and 16-Bit Pixel Port True-Color RAMDAC
- Two Phase-Locked-Loop (PLL) Synthesizers Provide Independently Controlled Video and Memory Clock Outputs
- Functionally Interchangeable with STG1703
- On-Chip PLL Clock Reference Requires Single External Crystal
- 16-Bit Pixel Port Supports VGA High-Color and True-Color Standards Up to 170 MHz
- Programmable Power-Down Features
- On-Chip Cyclic Redundancy Check (CRC) Test
- Data Sheet Available†

applications

- Screen resolutions (noninterlaced)
 - 1600 × 1280, 8 bit/pixel, 60 Hz
 - 1280 × 1024, 16 bit/pixel, 60 Hz
 - 1024 × 768, 16 bit/pixel, 85 Hz
 - 1024 × 768, 24 bit/pixel, packed, 70 Hz
 - 800 × 600, 24 bit/pixel, unpacked, 72 Hz
- True-color desktop, PC add-in cards

description

The TVP3703 is a super VGA (SVGA) compatible, true-color CMOS RAMDAC with integrated clock synthesizers that can provide the memory and pixel clock signals for a PC graphics subsystem. The video clock can be one of two VGA base frequencies or 14 VESA standard frequencies that can also be reprogrammed through the standard microport interface.

The memory clock output is also user programmable at frequencies up to 80 MHz. The pixel modes supported by the TVP3703 include:

- Serializing 16-bit pixel port providing 170 MHz 8-bit and 73 MHz 24-bit packed pixel modes using an internal PLL
- 16-bit pixel port providing faster high-color/true-color operation up to the 110-MHz sampling rate
- 8-bit pixel port giving standard SVGA and high-color/true-color modes up to the 110-MHz sampling rate

The 68-terminal plastic leaded chip carrier (PLCC) package is designed to be interchangeable with the STG1703.

AVAILABLE OPTIONS

T _A	SPEED	DAC RESOLUTION	PACKAGE
			CHIP CARRIER (FN)
0°C to 70°C	135 MHz	8 Bits	TVP3703-135CFN
	170 MHz	8 Bits	TVP3703-170CFN

† For the complete data sheet, refer to the Graphics and Imaging Data book (SLAD002).

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PRODUCT PREVIEW

TVP3703
VIDEO INTERFACE PALETTE
TRUE-COLOR CMOS RAMDAC
 XLAS100 - FEBRUARY 1995

functional block diagram

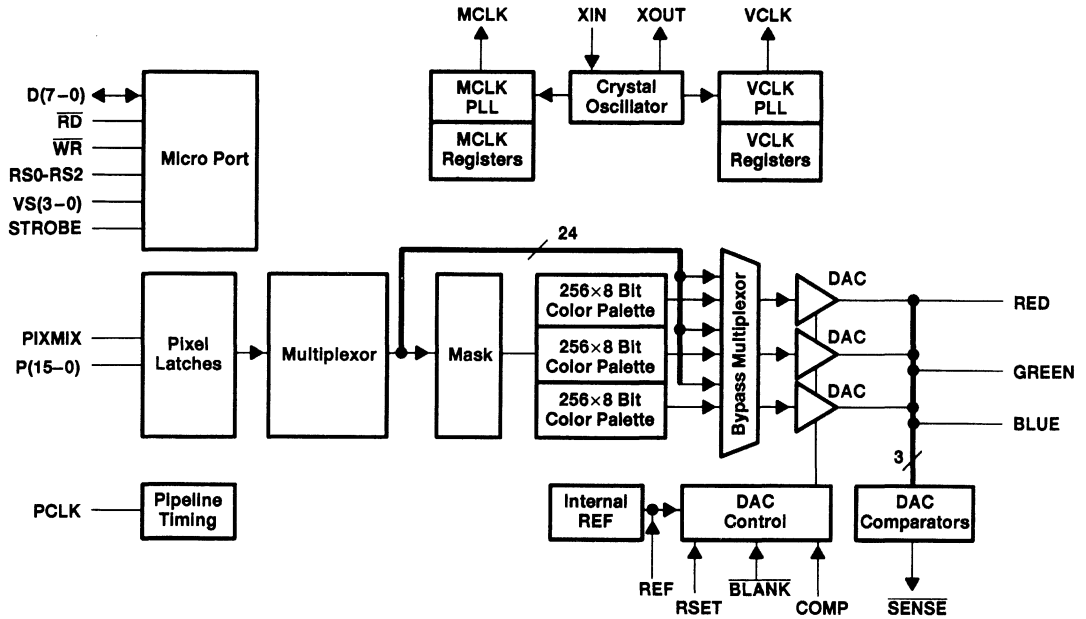


Figure 1. Functional Block Diagram

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7 Data Manuals

TLC32046C, TLC32046I, TLC32046M ***Data Manual***

Wide-Band Analog Interface Circuit

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1 Introduction

The TLC32046C, TLC32046I, and TLC32046M wide-band analog interface circuits (AIC) are a complete analog-to-digital and digital-to-analog interface system for advanced digital signal processors (DSPs) similar to the TMS32020, TMS320C25, and TMS320C30. The TLC32046C and TLC32046I offer a powerful combination of options under DSP control: three operating modes (dual-word [telephone interface], word, and byte) combined with two word formats (8 bits and 16 bits) and synchronous or asynchronous operation. It provides a high level of flexibility in that conversion and sampling rates, filter bandwidths, input circuitry, receive and transmit gains, and multiplexed analog inputs are under processor control.

This AIC features a

- band-pass switched-capacitor antialiasing input filter
- 14-bit-resolution A/D converter
- 14-bit-resolution D/A converter
- low-pass switched-capacitor output-reconstruction filter.

The antialiasing input filter comprises eighth-order and fourth-order CC-type (Chebyshev/elliptic transitional) low-pass and high-pass filters, respectively. The input filter is implemented in switched-capacitor technology and is preceded by a continuous time filter to eliminate any possibility of aliasing caused by sampled data filtering. When low-pass filtering is desired, the high-pass filter can be switched out of the signal path. A selectable auxiliary differential analog input is provided for applications where more than one analog input is required.

The output-reconstruction filter is an eighth-order CC-type (Chebyshev/elliptic transitional low-pass filter) followed by a second-order $(\sin x)/x$ correction filter and is implemented in switched-capacitor technology. This filter is followed by a continuous-time filter to eliminate images of the sample data signal. The on-board $(\sin x)/x$ correction filter can be switched out of the signal path using digital signal processor control.

The A/D and D/A architectures ensure no missing codes and monotonic operation. An internal voltage reference is provided to ease the design task and to provide complete control over the performance of the IC. The internal voltage reference is brought out to REF. Separate analog and digital voltage supplies and ground are provided to minimize noise and ensure a wide dynamic range. The analog circuit path contains only differential circuitry to keep noise to a minimum. The exception is the DAC sample-and-hold, which utilizes pseudo-differential circuitry.

The TLC32046C is characterized for operation from 0°C to 70°C, the TLC32046I is characterized for operation from -40°C to 85°C, and the TLC32046M is characterized for operation from -55°C to 125°C.

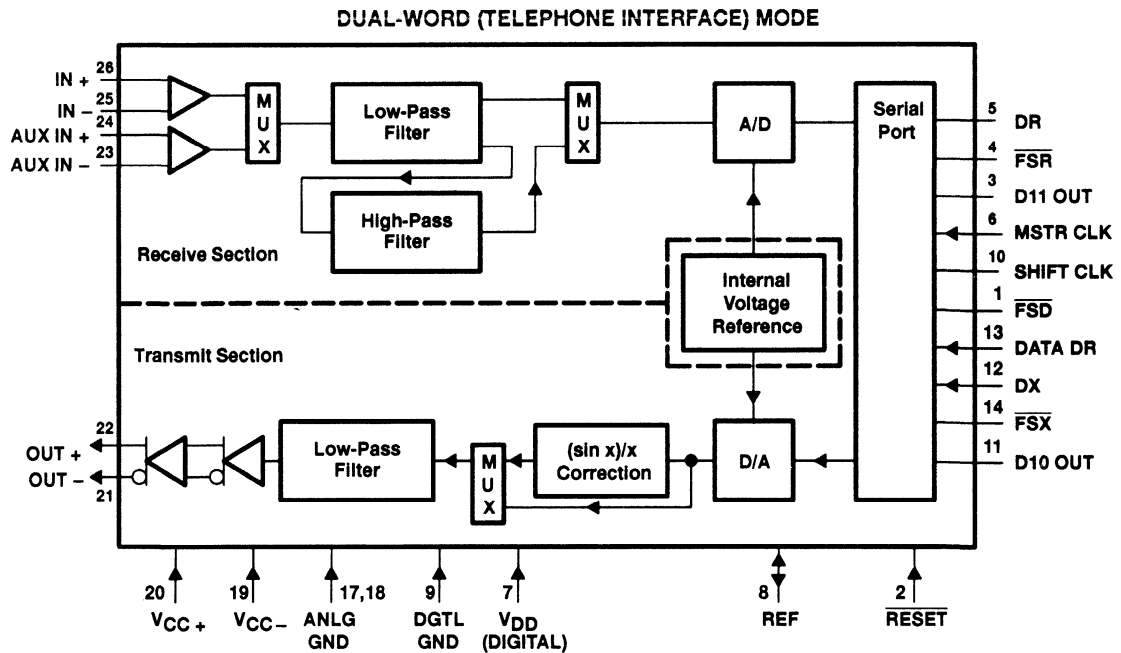
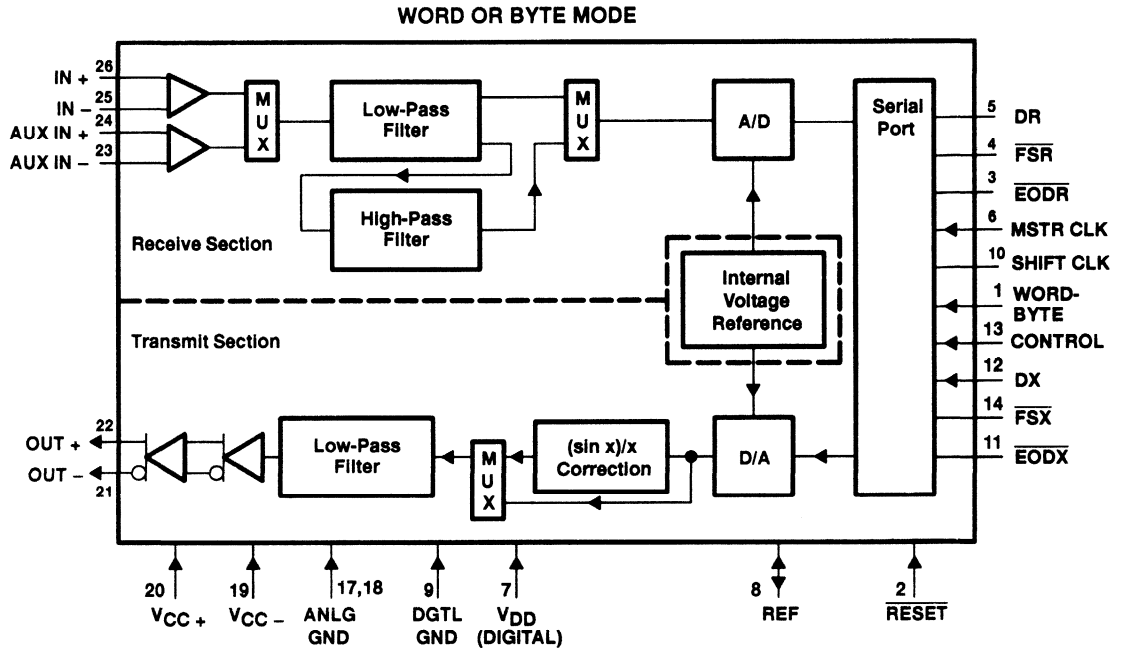
1.1 Features

- 14-Bit Dynamic Range ADC and DAC
- 16-Bit Dynamic Range Input With Programmable Gain
- Synchronous or Asynchronous ADC and DAC Sampling Rates Up to 25,000 Samples Per Second
- Programmable Incremental ADC and DAC Conversion Timing Adjustments
- Typical Applications
 - Speech Encryption for Digital Transmission
 - Speech Recognition and Storage Systems
 - Speech Synthesis
 - Modems at 8-kHz, 9.6-kHz, and 16-kHz Sampling Rates
 - Industrial Process Control
 - Biomedical Instrumentation
 - Acoustical Signal Processing
 - Spectral Analysis
 - Instrumentation Recorders
 - Data Acquisition
- Switched-Capacitor Antialiasing Input Filter and Output-Reconstruction Filter
- Three Fundamental Modes of Operation: Dual-Word (Telephone Interface), Word, and Byte
- 600-mil Wide N Package
- Digital Output in Twos Complement Format
- CMOS Technology

FUNCTION TABLE

DATA COMMUNICATIONS FORMAT	SYNCHRONOUS (CONTROL REGISTER BIT D5 = 1)	ASYNCHRONOUS (CONTROL REGISTER BIT D5 = 0)	FORCING CONDITION	DIRECT INTERFACE
16-bit format	Dual-word (telephone interface) mode	Dual-word (telephone interface) mode	Terminal 13 = 0 to 5 V Terminal 1 = 0 to 5 V	TMS32020, TMS320C25, TMS320C30
16-bit format	Word mode	Word mode	Terminal 13 = V_{CC-} (-5 V nom) Terminal 1 = V_{CC+} (5 V nom)	TMS32020, TMS320C25, TMS320C30, indirect interface to TMS320C10. (see Figure 7).
8-bit format (2 bytes required)	Byte mode	Byte mode	Terminal 13 = V_{CC-} (-5 V nom) Terminal 1 = V_{CC-} (-5 V nom)	TMS320C17

1.2 Functional Block Diagrams



FRAME SYNCHRONIZATION FUNCTIONS

Function	Frame Sync Output
Receiving serial data on DX from processor to internal DAC	$\overline{\text{FSX}}$ low
Transmitting serial data on DR from internal ADC to processor, primary communications	$\overline{\text{FSR}}$ low
Transmitting serial data on DR from Data-DR to processor, secondary communications in dual-word (telephone interface) mode only	$\overline{\text{FSD}}$ low

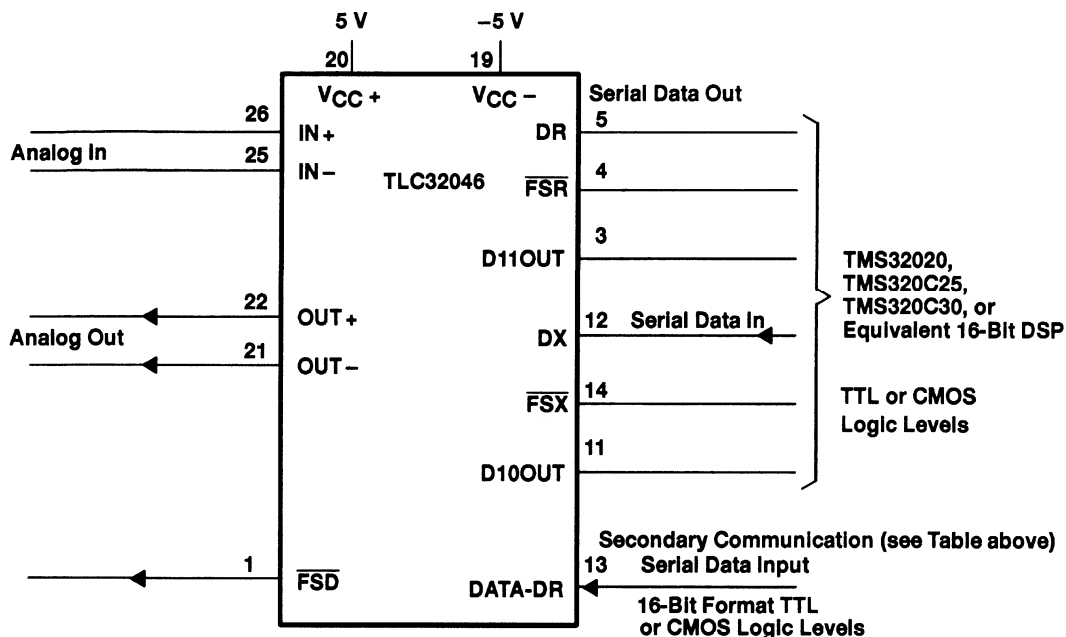


Figure 1-1. Dual-Word (Telephone Interface) Mode

When the DATA-DR/CONTROL input is tied to a logic signal source varying between 0 and 5 V, the TLC32046 is in the dual-word (telephone interface) mode. This logic signal is routed to the DR line for input to the DSP only when data frame synchronization ($\overline{\text{FSD}}$) outputs a low level. The $\overline{\text{FSD}}$ pulse duration is 16 shift clock pulses. Also, in this mode, the control register data bits D10 and D11 appear on D10OUT and D11OUT, respectively, as outputs.

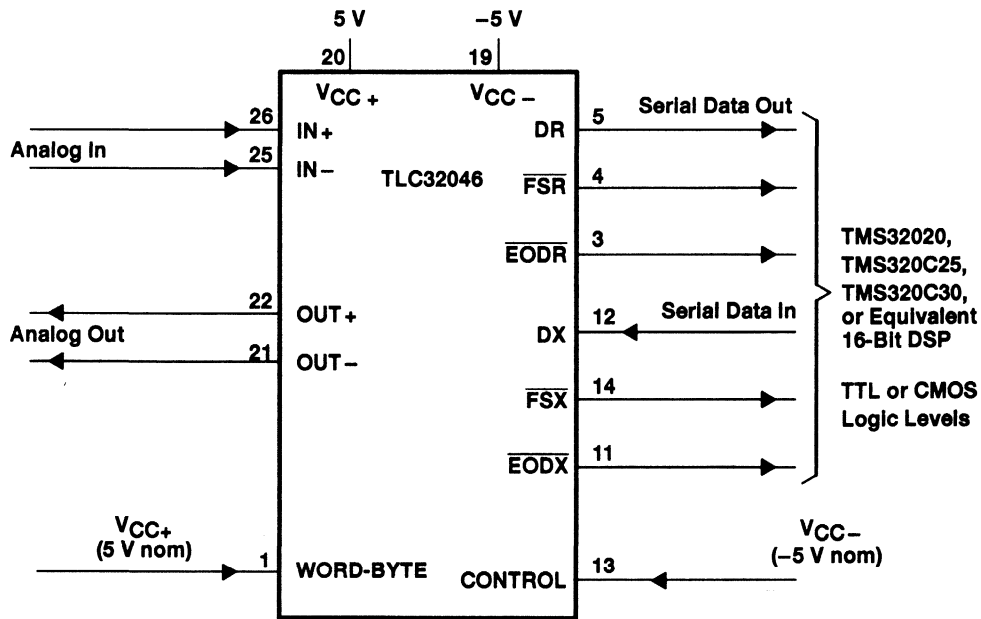


Figure 1-2. Word Mode

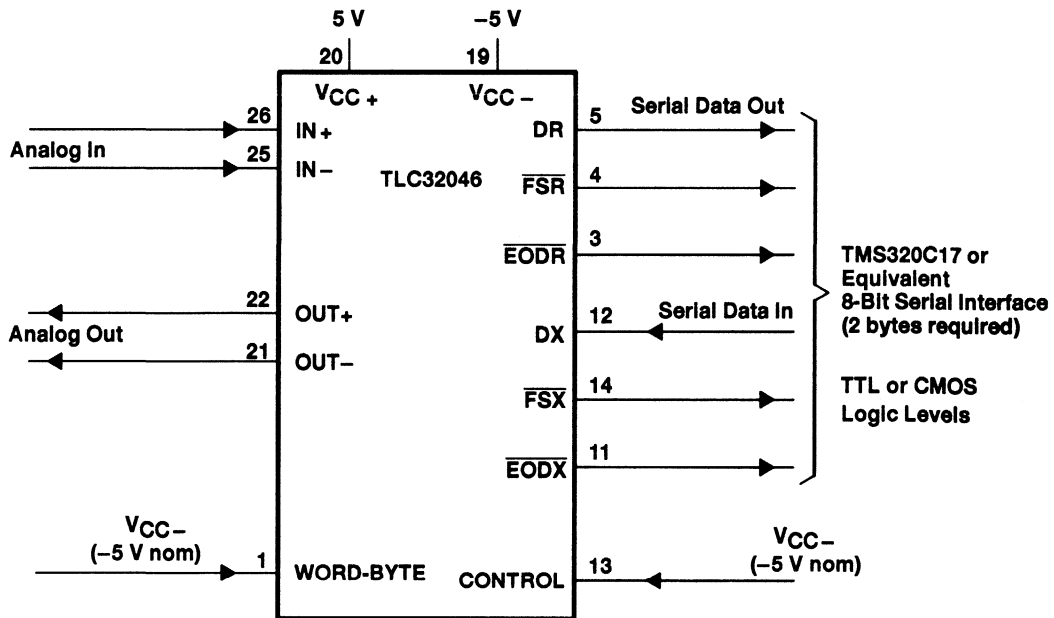
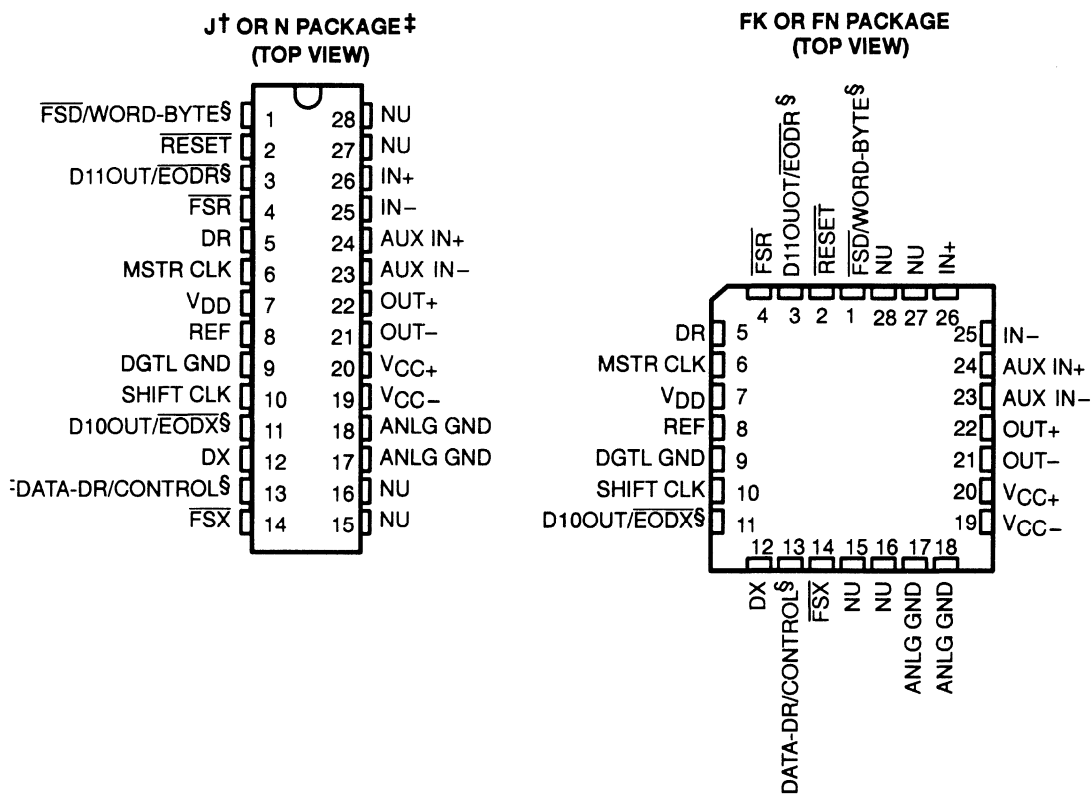


Figure 1-3. Byte Mode

The word or byte mode is selected by first connecting the DATA-DR/CONTROL input to V_{CC-} . \overline{FSD} /WORD-BYTE becomes an input and can then be used to select either word or byte transmission formats. The end-of-data transmit (\overline{EODX}) and the end-of-data receive (\overline{EODR}) signals respectively, are used to signal the end of word or byte communication (see the Terminal Functions section).

1.3 Terminal Assignments



NU - Nonusable; no external connection should be made to these terminals.

† Refer to the mechanical data for the JT package.

‡ 600-mil wide

§ The portion of the terminal name to the left of the slash is used for the dual-word (telephone interface) mode. The portion of the terminal name to the right of the slash is used for word-byte mode.

1.4 Ordering Information

AVAILABLE OPTIONS

T _A	PACKAGE			
	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)	CERAMIC DIP (J)	CHIP CARRIER (FK)
0°C to 70°C	TLC32046CFN	TLC32046CN		
-40°C to 85°C	TLC32046IFN	TLC32046IN		
-55°C to 125°C			TLC32046MJ	TLC32046MFK

1.5 Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANLG GND	17,18		Analog ground return for all internal analog circuits. Not internally connected to DGTL GND.
AUX IN+	24	I	Noninverting auxiliary analog input stage. AUX IN+ can be switched into the band-pass filter and ADC path via software control. If the appropriate bit in the control register is a 1, the auxiliary inputs replace the IN+ and IN- inputs. If the bit is a 0, the IN+ and IN- inputs are used (see the DX Serial Data Word Format).
AUX IN-	23	I	Inverting auxiliary analog input (see the above AUX IN+ description).
DATA-DR	13	I	The dual-word (telephone interface) mode, selected by applying an input logic level between 0 and 5 V to DATA-DR, allows this terminal to function as a data input. The data is then framed by the FSD signal and transmitted as an output to the DR line during secondary communication. The functions $\overline{\text{FSD}}$, D11OUT, and D10OUT are valid with this mode selection (see Table 2-1).
CONTROL			When CONTROL is tied to V_{CC-} , the device is in the word or byte mode. The functions WORD-BYTE, $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are valid in this mode. CONTROL is then used to select either the word or byte mode (see Function Table).
DR	5	O	DR is used to transmit the ADC output bits from the AIC to the TMS320 serial port. This transmission of bits from the AIC to the TMS320 serial port is synchronized with SHIFT CLK.
DX	12	I	DX is used to receive the DAC input bits and timing and control information from the TMS320. This serial transmission from the TMS320 serial port is synchronized with SHIFT CLK.
D10OUT	11	O	In the dual-word (telephone interface) mode, bit D10 of the control register is output to D10OUT. When the device is reset, bit D10 is initialized to 0 (see DX Serial Data Word Format). The output update is immediate upon changing bit D10.
$\overline{\text{EODX}}$			End-of-data transmit. During the word-mode timing, a low-going pulse occurs on $\overline{\text{EODX}}$ immediately after the 16 bits of DAC and control or register information have transmitted from the TMS320 serial port to the AIC. This signal can be used to interrupt a microprocessor upon completion of serial communications. Also, this signal can be used to strobe and enable external serial-to-parallel shift registers, latches, or external FIFO RAM and to facilitate parallel data bus communications between the DSP and the serial-to-parallel shift registers. During the byte-mode timing, this signal goes low after the first byte has been transmitted from the TMS320 serial port to the AIC and is kept low until the second byte has been transmitted. The TMS320C17 can use this low-going signal to differentiate first and second bytes.
D11OUT	3	O	In the dual-word (telephone interface) mode, bit D11 of the control register is output to D11OUT. When the device is reset, bit D11 is initialized to 0 (see DX Serial Data Word Format). The output update is immediate upon changing bit D11.
$\overline{\text{EODR}}$			End-of-data receive. During the word-mode timing, a low-going pulse occurs on $\overline{\text{EODR}}$ immediately after the 16 bits of A/D information have been transmitted from the AIC to the TMS320 serial port. This signal can be used to interrupt a microprocessor upon completion of serial communications. Also, this signal can be used to strobe and enable external serial-to-parallel shift registers, latches, or external FIFO RAM, and to facilitate parallel data bus communications between the DSP and the serial-to-parallel shift registers. During the byte-mode timing, this signal goes low after the first byte has been transmitted from the AIC to the TMS320 serial port and is kept low until the second byte has been transmitted. The TMS320C17 can use this low-going signal to differentiate between first and second bytes.

1.5 Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
DGTL	9		Digital ground for all internal logic circuits. Not internally connected to ANLG GND.
$\overline{\text{FSD}}$	1	O	Frame sync data. The $\overline{\text{FSD}}$ output remains high during primary communication. In the dual-word (telephone interface) mode, $\overline{\text{FSD}}$ is identical to $\overline{\text{FSX}}$ during secondary communication.
WORD-BYTE		I	WORD-BYTE allows differentiation between the word and byte data format (see DATA-DR/CONTROL and Table 2-1 for details).
$\overline{\text{FSR}}$	4	O	Frame sync receive. $\overline{\text{FSR}}$ is held low during bit transmission. When $\overline{\text{FSR}}$ goes low, the TMS320 serial port begins receiving bits from the AIC via DR of the AIC. The most significant DR bit is present on DR before $\overline{\text{FSR}}$ goes low (see Serial Port Sections and Internal Timing Configuration Diagrams).
$\overline{\text{FSX}}$	14	O	Frame sync transmit. When $\overline{\text{FSX}}$ goes low, the TMS320 serial port begins transmitting bits to the AIC via DX of the AIC. $\overline{\text{FSX}}$ is held low during bit transmission (see Serial Port Sections and Internal Timing Configuration Diagrams).
IN+	26	I	Noninverting input to analog input amplifier stage
IN-	25	I	Inverting input to analog input amplifier stage
MSTR CLK	6	I	The master clock signal is used to derive all the key logic signals of the AIC, such as the shift clock, the switched-capacitor filter clocks, and the A/D and D/A timing signals. The Internal Timing Configuration diagram shows how these key signals are derived. The frequencies of these signals are synchronous submultiples of the master clock frequency to eliminate unwanted aliasing when the sampled analog signals are transferred between the switched-capacitor filters and the ADC and DAC converters (see the Internal Timing Configuration).
OUT+	22	O	Noninverting output of analog output power amplifier. OUT+ drives transformer hybrids or high-impedance loads directly in a differential or a single-ended configuration.
OUT-	21	O	Inverting output of analog output power amplifier. OUT- is functionally identical with and complementary to OUT+.
REF	8	I/O	The internal voltage reference is brought out on REF. An external voltage reference can be applied to REF to override the internal voltage reference.
$\overline{\text{RESET}}$	2	I	A reset function is provided to initialize TA, TA', TB, RA, RA', RB (see Figure 2-1), and the control registers. This reset function initiates serial communications between the AIC and DSP. The reset function initializes all AIC registers, including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC registers are initialized to provide a 16-kHz data conversion rate for a 10.368-MHz master clock input signal. The conversion rate adjust registers, TA' and RA', are reset to 1. The CONTROL register bits are reset as follows (see AIC DX Data Word Format section): D11 = 0, D10 = 0, D9 = 1, D7 = 1, D6 = 1, D5 = 1, D4 = 0, D3 = 0, D2 = 1 The shift clock (SCLK) is held high during $\overline{\text{RESET}}$. This initialization allows normal serial-port communication to occur between the AIC and the DSP.
SHIFT CLK	10	O	The shift clock signal is obtained by dividing the master clock signal frequency by four. SHIFT CLK is used to clock the serial data transfers of the AIC.
VDD	7		Digital supply voltage, 5 V \pm 5%
VCC+	20		Positive analog supply voltage, 5 V \pm 5%
VCC-	19		Negative analog supply voltage, -5 V \pm 5%

2 Detailed Description

Table 2-1. Mode-Selection Function Table

DATA-DR/ CONTROL (Terminal 13)	$\overline{\text{FSD}}$ / WORD-BYTE (Terminal 1)	CONTROL REGISTER BIT (D5)	OPERATING MODE	SERIAL CONFIGURATION	DESCRIPTION
Data in (0 V to 5 V)	FSD out (0 V to 5 V)	1	Dual Word (Telephone Interface)	Synchronous, One 16-Bit Word	Terminal functions DATA-DR [†] , $\overline{\text{FSD}}$ [†] , D11OUT, and D10OUT are applicable in this configuration. $\overline{\text{FSD}}$ is asserted during secondary communication, but $\overline{\text{FSR}}$ is not asserted. However, $\overline{\text{FSD}}$ remains high during primary communication.
Data in (0 V to 5 V)	FSD out (0 V to 5 V)	0	Dual Word (Telephone Interface)	Synchronous, One 16-Bit Word	Terminal functions DATA-DR [†] , $\overline{\text{FSD}}$ [†] , D11OUT, and D10OUT are applicable in this configuration. $\overline{\text{FSD}}$ is asserted during secondary communication, but $\overline{\text{FSR}}$ is not asserted. However, $\overline{\text{FSD}}$ remains high during primary communication. If secondary communications occur while the A/D conversion is being transmitted from DR, $\overline{\text{FSD}}$ cannot go low, and data from DATA-DR cannot go onto DR.
$V_{\text{CC-}}$	$V_{\text{CC+}}$	1	WORD	Synchronous, One 16-Bit Word	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.
		0		Asynchronous, One 16-bit Word	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.
	$V_{\text{CC-}}$	1	BYTE	Synchronous, Two 8-Bit Bytes	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.
		0		Asynchronous, Two 8-Bit Bytes	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.

[†] DATA-DR/CONTROL has an internal pulldown resistor to -5 V, and $\overline{\text{FSD}}$ /WORD-BYTE has an internal pullup resistor to 5 V.

2.1 Internal Timing Configuration (see Figure 2–1)

All the internal timing of the AIC is derived from the high-frequency clock signal that drives the master clock input. The shift clock signal, which strobes the serial port data between the AIC and DSP, is derived by dividing the master clock input signal frequency by four.

The TX(A) counter and the TX(B) counter, which are driven by the master clock signal, determine the D/A conversion timing. Similarly, the RX(A) counter and the RX(B) counter determine the A/D conversion timing. In order for the low-pass switched-capacitor filter in the D/A path (see Functional Block Diagram) to meet its transfer function specifications, the frequency of its clock input must be 288 kHz. If the clock frequency is not 288 kHz, the filter transfer function frequencies are frequency-scaled by the ratios of the clock frequency to 288 kHz:

$$\text{Absolute Frequency (kHz)} = \frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{288} \quad (1)$$

For Low-Pass SCF $f_{\text{clock}} > 288$ kHz, please call the factory.

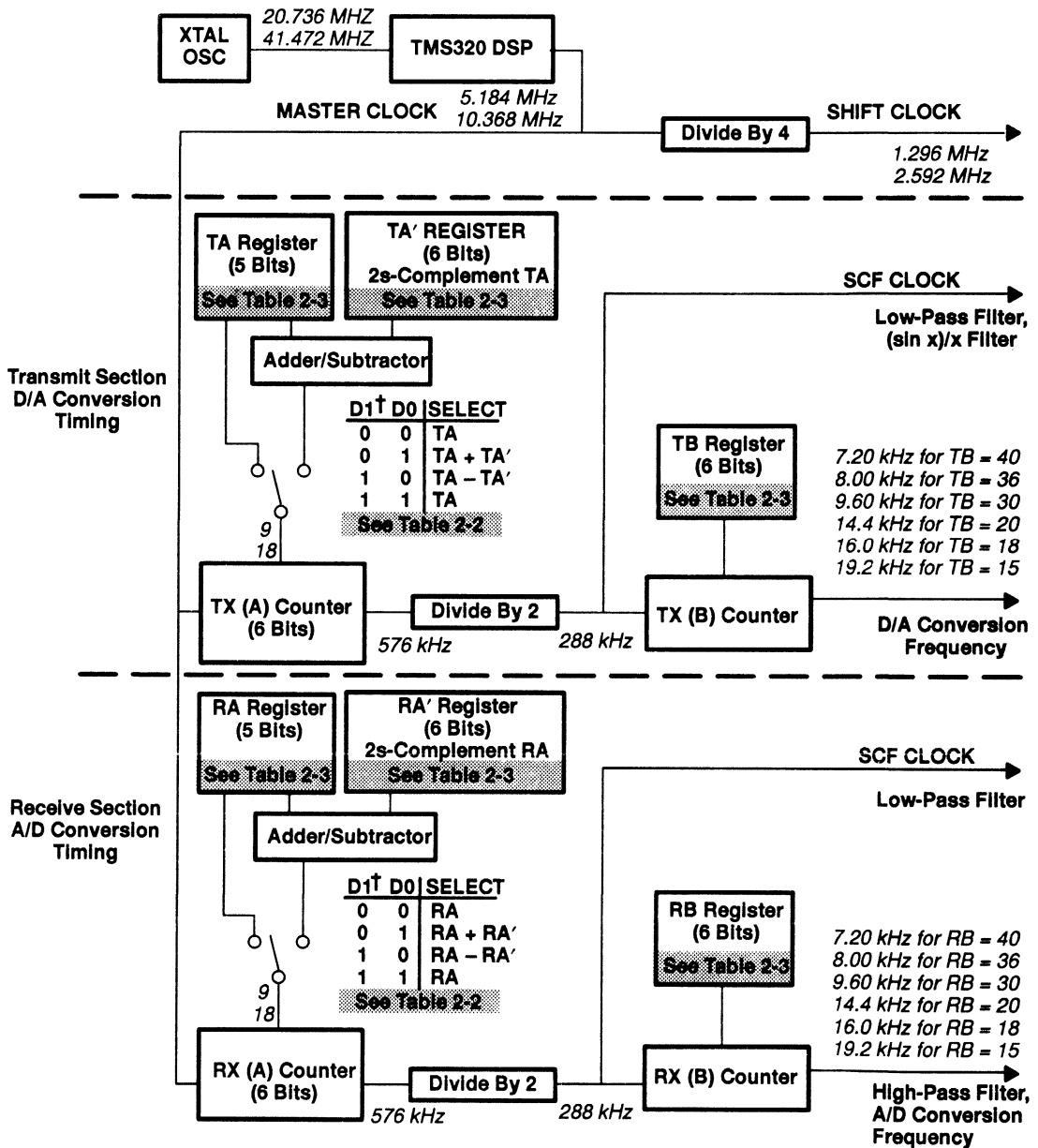
To obtain the specified filter response, the combination of master clock frequency and the TX(A) counter and the RX(A) counter values must yield a 288-kHz switched-capacitor clock signal. This 288-kHz clock signal can then be divided by the TX(B) counter to establish the D/A conversion timing.

The transfer function of the band-pass switched-capacitor filter in the A/D path (see Functional Block Diagram) is a composite of its high-pass and low-pass transfer functions. When the shift-clock frequency (SCF) is 288 kHz, the high-frequency roll-off of the low-pass section will meet the band-pass filter transfer function specification. Otherwise, the high-frequency roll-off is frequency-scaled by the ratio of the high-pass section SCF clock to 288 kHz (see Figure 5–5). The low-frequency roll-off of the high-pass section meets the band-pass filter transfer function specification when the A/D conversion rate is 16 kHz. If not, the low-frequency roll-off of the high-pass section is frequency-scaled by the ratio of the A/D conversion rate to 16 kHz.

The TX(A) counter and the TX(B) counter are reloaded each D/A conversion period, while the RX(A) counter and the RX(B) counter are reloaded every A/D conversion period. The TX(B) counter and the RX(B) counter are loaded with the values in the TB and RB registers, respectively. Via software control, the TX(A) counter can be loaded with the TA register, the TA register less the TA' register, or the TA register plus the TA' register. By selecting the TA register less the TA' register option, the upcoming conversion timing occurs earlier by an amount of time that equals TA' times the signal period of the master clock. If the TA register plus the TA' register option is executed, the upcoming conversion timing occurs later by an amount of time that equals TA' times the signal period of the master clock. Thus, the D/A conversion timing can be advanced or retarded. An identical ability to alter the A/D conversion timing is provided. However, the RX(A) counter can be programmed via software control with the RA register, the RA register less the RA' register, or the RA register plus the RA' register.

The ability to advance or retard conversion timing is particularly useful for modem applications. This feature allows controlled changes in the A/D and D/A conversion timing and can be used to enhance signal-to-noise performance, to perform frequency-tracking functions, and to generate nonstandard modem frequencies.

If the transmit and receive sections are configured to be synchronous, then the low-pass and band-pass switched-capacitor filter clocks are derived from the TX(A) counter. Also, both the D/A and A/D conversion timings are derived from the TX(A) counter and the TX(B) counter. When the transmit and receive sections are configured to be asynchronous, the RX(A) counter, RX(B) counter, RA register, RA' register, and RB registers are not used.



† These control bits are described in the DX Serial Data Word Format section.

- NOTES:
- Tables 2-2 and 2-3 are primary and secondary communication protocols, respectively.
 - In synchronous operation, RA, RA', RB, RX(A), and RX(B) are not used. TA, TA', TB, TX(A), and TX(B) are used instead.
 - Items in italics refer only to frequencies and register contents, which are variable. A crystal oscillator driving 20.736 MHz into the TMS320-series DSP provides a master clock frequency of 5.184 MHz. The TLC32046 produces a shift clock frequency of 1.296 MHz. If the TX(A) register contents equal 9, the SCF clock frequency is 288 kHz, and the D/A conversion frequency is 288 kHz ÷ T(B).

Figure 2-1. Asynchronous Internal Timing Configuration

2.2 Analog Input

Two pairs of analog inputs are provided. Normally, the IN+ and IN– input pair is used; however, the auxiliary input pair, AUX IN+ and AUX IN–, can be used if a second input is required. Since sufficient common-mode range and rejection are provided, each input set can be operated in differential or single-ended modes. The gain for the IN+, IN–, AUX IN+, and AUX IN– inputs can be programmed to 1, 2, or 4 (see Table 4–1). Either input circuit can be selected via software control. Multiplexing is controlled with the D4 bit (enable/disable AUX IN+ and AUX IN–) of the secondary DX word (see Table 2–3). The multiplexing requires a 2-ms wait at $SCF = 288 \text{ kHz}$ (see Figure 5–3) for a valid output signal. A wide dynamic range is ensured by the differential internal analog architecture and the separate analog and digital voltage supplies and grounds.

2.3 A/D Band-Pass Filter, Clocking, and Conversion Timing

The receive-channel A/D high-pass filter can be selected or bypassed via software control (see Functional Block Diagram). The frequency response of this filter is found in the electrical characteristic section. This response results when the switched-capacitor filter clock frequency is 288 kHz and the A/D sample rate is 16 kHz. Several possible options can be used to attain a 288-kHz switched-capacitor filter clock. When the filter clock frequency is not 288 kHz, the low-pass filter transfer function is frequency-scaled by the ratio of the actual clock frequency to 288 kHz (see Typical Characteristics section). The ripple bandwidth and 3-dB low-frequency roll-off points of the high-pass section are 300 Hz and 200 Hz, respectively. However, the high-pass section low-frequency roll-off is frequency-scaled by the ratio of the A/D sample rate to 16 kHz.

Figure 2–1 and the DX serial data word format sections of this data manual indicate the many options for attaining a 288-kHz band-pass switched-capacitor filter clock. These sections indicate that the RX(A) counter can be programmed to give a 288-kHz band-pass switched-capacitor filter clock for several master clock input frequencies.

The A/D conversion rate is attained by frequency-dividing the band-pass switched-capacitor filter clock with the RX(B) counter. Unwanted aliasing is prevented because the A/D conversion rate is an integer submultiple of the band-pass switched-capacitor filter sampling rate, and the two rates are synchronously locked.

2.4 A/D Converter

Fundamental performance specifications for the receive channel ADC circuitry are in the electrical characteristic section of this data manual. The ADC circuitry, using switched-capacitor techniques, provides an inherent sample-and-hold function.

2.5 Analog Output

The analog output circuitry is an analog output power amplifier. Both noninverting and inverting amplifier outputs are brought out of the IC. This amplifier can drive transformer hybrids or low-impedance loads directly in either a differential or single-ended configuration.

2.6 D/A Low-Pass Filter, Clocking, and Conversion Timing

The frequency response results when the low-pass switched-capacitor filter clock frequency is 288 kHz (see equation 1). Like the A/D filter, the transfer function of this filter is frequency-scaled when the clock frequency is not 288 kHz (see Typical Characteristics section). A continuous-time filter is provided on the output of the low-pass filter to eliminate the periodic sample data signal information, which occurs at multiples of the 288-kHz switched-capacitor clock feedthrough.

The D/A conversion rate is attained by frequency-dividing the 288-kHz switched-capacitor filter clock with the T(B) counter. Unwanted aliasing is prevented because the D/A conversion rate is an integer submultiple of the switched-capacitor low-pass filter sampling rate, and the two rates are synchronously locked.

2.7 D/A Converter

Fundamental performance specifications for the transmit channel DAC circuitry are in the electrical characteristic section. The DAC has a sample-and-hold function that is realized with a switched-capacitor ladder.

2.8 Serial Port

The serial port has four possible configurations summarized in the function table on page 1–2. These configurations are briefly described below.

- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS320C17. The communications protocol is two 8-bit bytes.
- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS32020, TMS320C25, and TMS320C30. The communications protocol is one 16-bit word.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS320C17. The communications protocol is two 8-bit bytes.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS32020, TMS320C25, TMS320C30, or two SN74299 serial-to-parallel shift registers, which can interface in parallel to the TMS32010, TMS320C15, to any other digital signal processor, or to external FIFO circuitry. The communications protocol is one 16-bit word.

2.9 Synchronous Operation

When the transmit and receive sections are operated synchronously, the low-pass filter clock drives both low-pass and band-pass filters (see Functional Block Diagram). The A/D conversion timing is derived from and equal to the D/A conversion timing. When data bit D5 in the control register is a logic 1, transmit and receive sections are synchronous. The band-pass switched-capacitor filter and the A/D converter timing are derived from the TX(A) counter, the TX(B) counter, and the TA and TA' registers. In synchronous operation, both the A/D and the D/A channels operate from the same frequencies. The \overline{FSX} and the \overline{FSR} timing is identical during primary communication, but \overline{FSR} is not asserted during secondary communication because there is no new A/D conversion result.

2.9.1 One 16-Bit Word (Dual-Word [Telephone Interface] or Word Mode)

The serial port interfaces directly with the serial ports of the TMS32020, TMS320C25, and the TMS320C30, and communicates in one 16-bit word. The operation sequence is as follows:

1. The \overline{FSX} and \overline{FSR} pins are brought low by the TLC32046 AIC.
2. One 16-bit word is transmitted and one 16-bit word is received.
3. \overline{FSX} and \overline{FSR} are brought high.
4. \overline{EODX} and \overline{EODR} emit low-going pulses one shift clock wide. \overline{EODX} and \overline{EODR} are valid in the word or byte mode only.

If the device is in the dual-word (telephone interface) mode, \overline{FSD} goes low during the secondary communication period and enables the data word received at the DATA-DR/CONTROL input to be routed to the DR line. The secondary communication period occurs four shift clocks after completion of primary communications.

2.9.2 Two 8-Bit Bytes (Byte Mode)

The serial port interfaces directly with the serial port of the TMS320C17 and communicates in two 8-bit bytes. The operation sequence is as follows:

1. \overline{FSX} and \overline{FSR} are brought low.
2. One 8-bit word is transmitted and one 8-bit word is received.
3. \overline{EODX} and \overline{EODR} are brought low.
4. \overline{FSX} and \overline{FSR} emit positive frame-sync pulses that are four shift clock cycles wide.
5. One 8-bit byte is transmitted and one 8-bit byte is received.
6. \overline{FSX} and \overline{FSR} are brought high.
7. \overline{EODX} and \overline{EODR} are brought high.

2.9.3 Synchronous Operating Frequencies

The synchronous operating frequencies are determined by the following equations.

Switched capacitor filter (SCF) frequencies (see Figure 2–1):

$$\text{Low-pass SCF clock frequency (D/A and A/D channels)} = \frac{\text{master clock frequency}}{T(A) \times 2}$$

$$\text{High-pass SCF clock frequency (A/D channel)} = \text{A/D conversion frequency}$$

$$\begin{aligned} \text{Conversion frequency (A/D and D/A channels)} &= \frac{\text{low-pass SCF clock frequency}}{T(B)} \\ &= \frac{\text{master clock frequency}}{T(A) \times 2 \times T(B)} \end{aligned}$$

NOTE: T(A), T(B), R(A), and R(B) are the contents of the TA, TB, RA, and RB registers, respectively.

2.10 Asynchronous Operation

When the transmit and the receive sections are operated asynchronously, the low-pass and band-pass filter clocks are independently generated from the master clock. The D/A and the A/D conversion timing is also determined independently.

D/A timing is set by the counters and registers described in synchronous operation, but the RA and RB registers are substituted for the TA and TB registers to determine the A/D channel sample rate and the A/D path switched-capacitor filter frequencies. Asynchronous operation is selected by control register bit D5 being zero.

2.10.1 One 16-Bit Word (Word Mode)

The serial port interfaces directly with the serial ports of the TMS32020, TMS320C25, and TMS320C30 and communicates with 16-bit word formats. The operation sequence is as follows:

1. \overline{FSX} or \overline{FSR} are brought low by the TLC32046 AIC.
2. One 16-bit word is transmitted or one 16-bit word is received.
3. \overline{FSX} or \overline{FSR} are brought high.
4. \overline{EODX} or \overline{EODR} emit low-going pulses one shift clock wide. \overline{EODX} and \overline{EODR} are valid in either the word or byte mode only.

2.10.2 Two 8-Bit Bytes (Byte Mode)

The serial port interfaces directly with the serial port of the TMS320C17 and communicates in two 8-bit bytes. The operating sequence is as follows:

1. \overline{FSX} or \overline{FSR} are brought low by the TLC32046 AIC.
2. One byte is transmitted or received.
3. \overline{EODX} or \overline{EODR} are brought low.
4. \overline{FSX} or \overline{FSR} are brought high for four shift clock periods and then brought low.
5. The second byte is transmitted or received.
6. \overline{FSX} or \overline{FSR} are brought high.
7. \overline{EODX} or \overline{EODR} are brought high.

2.10.3 Asynchronous Operating Frequencies

The asynchronous operating frequencies are determined by the following equations.

Switched-capacitor filter frequencies (see Figure 2–1):

$$\text{Low-pass D/A SCF clock frequency} = \frac{\text{master clock frequency}}{T(A) \times 2}$$

$$\text{Low-pass A/D SCF clock frequency} = \frac{\text{master clock frequency}}{R(A) \times 2}$$

$$\text{High-pass SCF clock frequency (A/D channel)} = \text{A/D conversion frequency} \quad (2)$$

Conversion frequency:

$$\text{D/A conversion frequency} = \frac{\text{low-pass D/A SCF clock frequency}}{T(B)}$$

$$\text{A/D conversion frequency} = \frac{\text{low-pass A/D SCF clock frequency (for low pass receive filter)}}{R(B)} \quad (3)$$

NOTE: T(A), T(B), R(A), and R(B) are the contents of the TA, TB, RA, and RB registers, respectively.

2.11 Operation of TLC32046 With Internal Voltage Reference

The internal reference of the TLC32046 eliminates the need for an external voltage reference and provides overall circuit cost reduction. The internal reference eases the design task and provides complete control of the IC performance. The internal reference is brought out to REF. To keep the amount of noise on the reference signal to a minimum, an external capacitor can be connected between REF and ANLG GND.

2.12 Operation of TLC32046 With External Voltage Reference

REF can be driven from an external reference circuit. This external circuit must be capable of supplying 250 μA and must be protected adequately from noise and crosstalk from the analog input.

2.13 Reset

A reset function is provided to initiate serial communications between the AIC and DSP and to allow fast, cost-effective testing during manufacturing. The reset function initializes all AIC registers, including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC is initialized. This initialization allows normal serial port communications activity to occur between AIC and DSP (see AIC DX Data Word Format section). After RESET, TA=TB=RA=RB=18 (or 12 hexadecimal), TA'=RA'=01 (hexadecimal), the A/D high-pass filter is inserted, the loop-back function is deleted, AUX IN+ and AUX IN- are disabled, transmit and receive sections are in synchronous operation, programmable gain is set to 1, the on-board (sin x)/x correction filter is not selected, D10OUT is set to 0, and D11OUT is set to 0.

2.14 Loopback

This feature allows the circuit to be tested remotely. In loopback, OUT+ and OUT- are internally connected to IN+ and IN-. The DAC bits (D15 to D2), which are transmitted to DX, can be compared with the ADC bits (D15 to D2), received from DR. The bits on DR equal the bits on DX. However, there is some difference in these bits due to the ADC and DAC output offsets.

The loopback feature is implemented with digital signal processor control by transmitting a logic 1 for data bit D3 in the DX secondary communication to the control register (see Table 2-3).

2.15 Communications Word Sequence

In the dual-word (telephone interface) mode, there are two data words that are presented to the DSP or μP from the DR terminal. The first data word is the ADC conversion result occurring during the FSR time, and the second is the serial data applied to DATA-DR during the FSD time. FSR is not asserted during secondary communications and FSD is not asserted during primary communications.

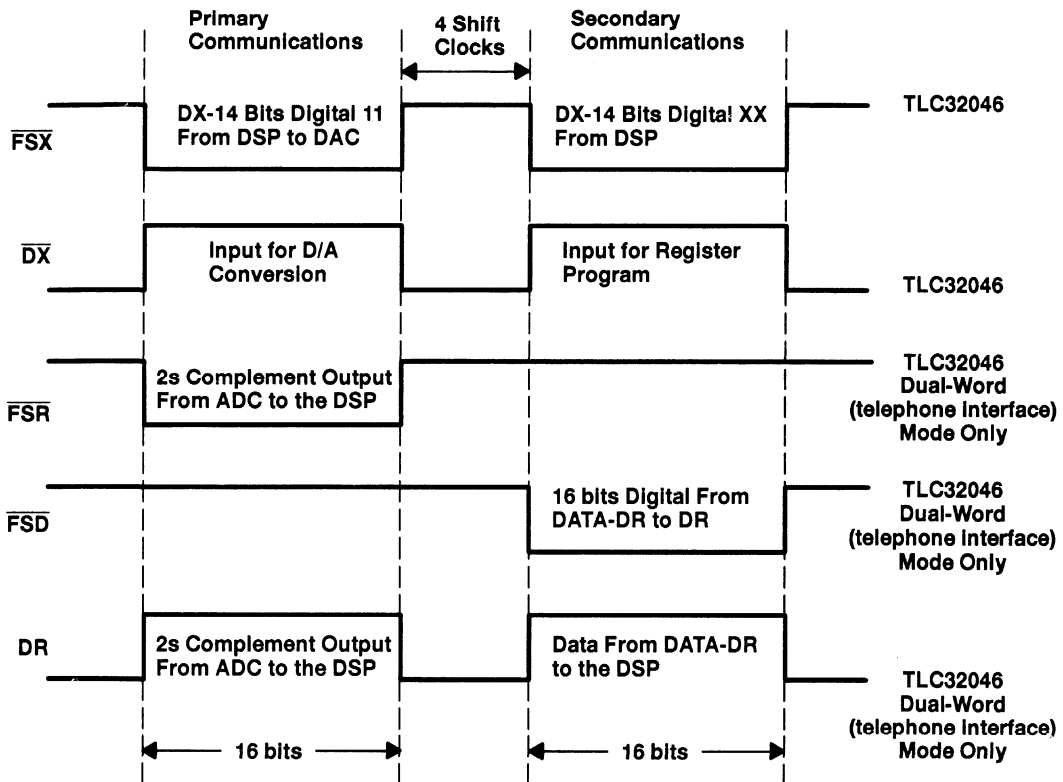
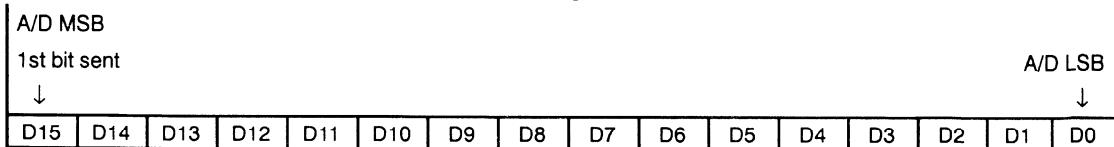


Figure 2-2. Primary and Secondary Communications Word Sequence

2.15.1 DR Word Bit Pattern

The data word is the 14-bit conversion result of the receive channel to the processor in 2s complement format. With 16-bit processors, the data is 16 bits long with the two LSBs at zero.



2.15.2 Primary DX Word Bit Pattern

Using 8-bit processors, the data word is transmitted in the same order as one 16-bit word, but as two bytes with the two LSBs of the second byte set to zero.

A/D OR D/A MSB															
1st bit sent				1st bit sent of 2nd byte								A/D or D/A LSB			
↓				↓								↓			
D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0

Table 2–2. Primary DX Serial Communication Protocol

FUNCTIONS	D1	D0
D15 (MSB)-D2 → DAC Register. TA → TX(A), RA → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1).	0	0
D15 (MSB)-D2 → DAC Register. TA+TA' → TX(A), RA+RA' → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1). The next D/A and A/D conversion period is changed by the addition of TA' and RA' master clock cycles, in which TA' and RA' can be positive, negative, or zero (refer to Table 2–4).	0	1
D15 (MSB)-D2 → DAC Register. TA-TA' → TX(A), RA-RA' → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1). The next D/A and A/D conversion period is changed by the subtraction of TA' and RA' master clock cycles, in which TA' and RA' can be positive, negative, or zero (refer to Table 2–4).	1	0
D15 (MSB)-D2 → DAC Register. TA → TX(A), RA → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1). After a delay of four shift cycles, a secondary transmission follows to program the AIC to operate in the desired configuration. In the telephone interface mode, data on DATA DR is routed to DR during secondary transmission.	1	1

NOTE: Setting the two least significant bits to 1 in the normal transmission of DAC information (primary communications) to the AIC initiates secondary communications upon completion of the primary communications. When the primary communication is complete, F_{SX} remains high for four SHIFT CLOCK cycles and then goes low and initiates the secondary communication. The timing specifications for the primary and secondary communications are identical. In this manner, the secondary communication, if initiated, is interleaved between successive primary communications. This interleaving prevents the secondary communication from interfering with the primary communications and DAC timing. This prevents the AIC from skipping a DAC output. F_{SR} is not asserted during secondary communications activity. However, in the dual-word (telephone interface) mode, F_{SD} is asserted during secondary communications but not during primary communications.

2.15.3 Secondary DX Word Bit Pattern

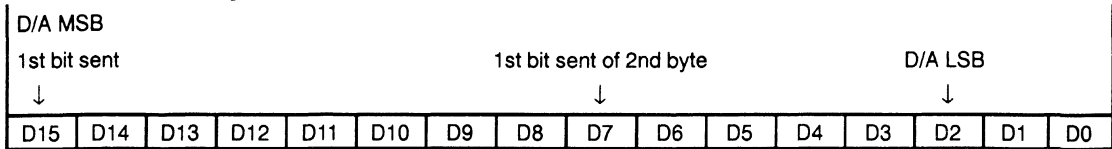


Table 2–3. Secondary DX Serial Communication Protocol

FUNCTIONS	D1	D0
D13 (MSB)-D9 → TA , 5 bits unsigned binary (see Figure 2–1). D6 (MSB)-D2 → RA, 5 bits unsigned binary (see Figure 2–1). D15, D14, D8, and D7 are unassigned.	0	0
D14 (sign bit)-D9 → TA', 6 bits 2s complement (see Figure 2–1). D7 (sign bit)-D2 → RA', 6 bits 2s complement (see Figure 2–1). D15 and D8 are unassigned.	0	1
D14 (MSB)-D9 → TB, 6 bits unsigned binary (see Figure 2–1). D7 (MSB)-D2 → RB, 6 bits unsigned binary (see Figure 2–1). D15 and D8 are unassigned.	1	0
D2 = 0/1 deletes/inserts the A/D high-pass filter. D3 = 0/1 deletes/inserts the loopback function. D4 = 0/1 disables/enables AUX IN+ and AUX IN–. D5 = 0/1 asynchronous/synchronous transmit and receive sections. D6 = 0/1 gain control bits (see Table 4–1). D7 = 0/1 gain control bits (see Table 4–1). D9 = 0/1 delete/insert on-board second-order (sinx)/x correction filter D10 = 0/1 output to D10OUT (dual-word (telephone interface) mode) D11 = 0/1 output to D11OUT (dual-word (telephone interface) mode) D8, D12–D15 are unassigned.	1	1

2.16 Reset Function

A reset function is provided to initiate serial communications between the AIC and DSP. The reset function initializes all AIC registers, including the control register. After power has been applied to the AIC, a negative-going pulse on RESET initializes the AIC registers to provide a 16-kHz A/D and D/A conversion rate for a 10.368-MHz master clock input signal. Also, the pass-bands of the A/D and D/A filters are 300 Hz to 7200 Hz and 0 Hz to 7200 Hz, respectively; therefore, the filter bandwidths are half those shown in the filter transfer function specification section. The AIC, except the CONTROL register, is initialized as follows (see AIC DX Data Word Format section):

REGISTER	TA	TA'	TB	RA	RA'	RB
INITIALIZED VALUE (HEX)	12	01	12	12	01	12

The CONTROL register bits are reset as follows (see Table 2–3):

$$D11 = 0, D10 = 0, D9 = 1, D7 = 1, D6 = 1, D5 = 1, D4 = 0, D3 = 0, D2 = 1$$

This initialization allows normal serial port communications to occur between the AIC and the DSP. If the transmit and receive sections are configured to operate synchronously and the user wishes to program different conversion rates, only the TA, TA', and TB register need to be programmed. Both transmit and receive timing are synchronously derived from these registers (see the Terminal Functions and DX Serial Data Word Format sections).

Figure 2–3 shows a circuit that provides a reset on power-up when power is applied in the sequence given in the power-up sequence section. The circuit depends on the power supplies reaching their recommended values a minimum of 800 ns before the capacitor charges to 0.8 V above DGTL GND.

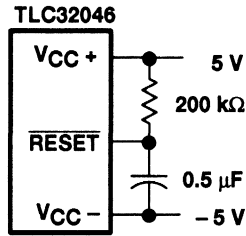


Figure 2–3. Reset on Power-Up Circuit

2.17 Power-Up Sequence

To ensure proper operation of the AIC and as a safeguard against latch-up, it is recommended that Schottky diodes with forward voltages less than or equal to 0.4 V be connected from V_{CC-} to ANLG GND and from V_{CC-} to DGTL GND. In the absence of such diodes, power is applied in the following sequence: ANLG GND and DGTL GND, V_{CC-} , then V_{CC+} and V_{DD} . Also, no input signal is applied until after power-up.

2.18 AIC Register Constraints

The following constraints are placed on the contents of the AIC registers:

1. TA register must be ≥ 4 in word mode (WORD/BYTE= high).
2. TA register must be ≥ 5 in byte mode (WORD/BYTE= low).
3. TA' register can be either positive, negative, or zero.
4. RA register must be ≥ 4 in word mode (WORD/BYTE = high).
5. RA register must be ≥ 5 in byte mode (WORD/BYTE = low).
6. RA' register can be either positive, negative, or zero.
7. (TA register \pm TA' register) must be > 1 .
8. (RA register \pm RA' register) must be > 1 .
9. TB register must be ≥ 15 .
10. RB register must be ≥ 15 .

2.19 AIC Responses to Improper Conditions

The AIC has provisions for responding to improper conditions. These improper conditions and the response of the AIC to these conditions are presented in Table 2–4.

Table 2–4. AIC Responses to Improper Conditions

IMPROPER CONDITION	AIC RESPONSE
TA register + TA' register = 0 or 1 TA register – TA' register = 0 or 1	Reprogram TX(A) counter with TA register value
TA register + TA' register < 0	MODULO 64 arithmetic is used to ensure that a positive value is loaded into TX(A) counter, i.e., TA register + TA' register + 40 HEX is loaded into TX(A) counter.
RA register + RA' register = 0 or 1 RA register – RA' register = 0 or 1	Reprogram RX(A) counter with RA register value
RA register + RA' register = 0 or 1	MODULO 64 arithmetic is used to ensure that a positive value is loaded into RX(A) counter, i.e., RA register + RA' register + 40 HEX is loaded into RX(A) counter.
TA register = 0 or 1 RA register = 0 or 1	AIC is shut down. Reprogram TA or RA registers after a reset.
TA register < 4 in word mode TA register < 5 in byte mode RA register < 4 in word mode RA register < 5 in byte mode	The AIC serial port no longer operates. Reprogram TA or RA registers after a reset.
TB register < 15	Reprogram TB register with 12 HEX
RB register < 15	Reprogram RB register with 12 HEX
AIC and DSP cannot communicate	Hold last DAC output

2.20 Operation With Conversion Times Too Close Together

If the difference between two successive D/A conversion frame syncs is less than 1/25 kHz, the AIC operates improperly. In this situation, the second D/A conversion frame sync occurs too quickly, and there is not enough time for the ongoing conversion to be completed. This situation can occur if the A and B registers are improperly programmed or if the A + A' register result is too small. When incrementally adjusting the conversion period via the A + A' register options, the designer should not violate this requirement (see Figure 2–4).

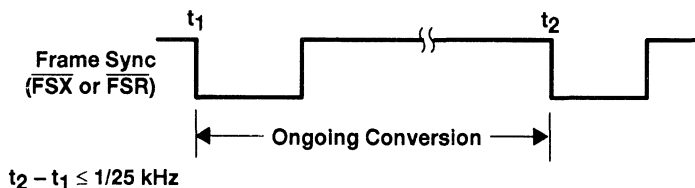


Figure 2–4. Conversion Times Too Close Together

2.21 More Than One Receive Frame Sync Occurring Between Two Transmit Frame Syncs – Asynchronous Operation

When incrementally adjusting the conversion period via the A + A' or A – A' register options, a specific protocol is followed. The command to use the incremental conversion period adjust option is sent to the AIC during an FSX frame sync. The ongoing conversion period is then adjusted; however, either receive conversion period A or conversion period B can be adjusted. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. If there is sufficient time between t_1 and t_2 , the receive conversion period adjustment is performed during receive conversion period A. Otherwise, the adjustment is performed during receive conversion period B.

The adjustment command only adjusts one transmit conversion period and one receive conversion period. To adjust another pair of transmit and receive conversion periods, another command must be issued during a subsequent FSX frame (see Figure 2–5).

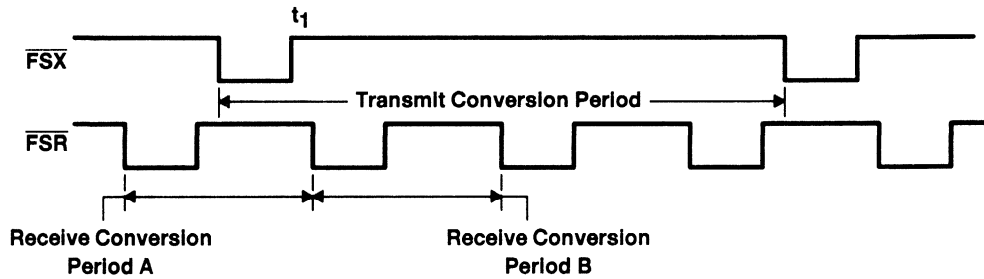


Figure 2-5. More Than One Receive Frame Sync Between Two Transmit Frame Syncs

2.22 More Than One Transmit Frame Sync Occurring Between Two Receive Frame Syncs – Asynchronous Operation

When incrementally adjusting the conversion period via the $A + A'$ or $A - A'$ register options, a specific protocol must be followed. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. The command to use the incremental conversion period adjust options is sent to the AIC during an \overline{FSX} frame sync. The ongoing transmit conversion period is then adjusted. However, three possibilities exist for the receive conversion period adjustment as shown in Figure 2-6. When the adjustment command is issued during transmit conversion period A, receive conversion period A is adjusted if there is sufficient time between t_1 and t_2 . If there is not sufficient time between t_1 and t_2 , receive conversion period B is adjusted. The third option is that the receive portion of an adjustment command can be ignored if the adjustment command is sent during a receive conversion period, which is adjusted due to a prior adjustment command. For example, if adjustment commands are issued during transmit conversion periods A, B, and C, the first two commands may cause receive conversion periods A and B to be adjusted, while the third receive adjustment command is ignored. The third adjustment command is ignored since it was issued during receive conversion period B, which already is adjusted via the transmit conversion period B adjustment command.

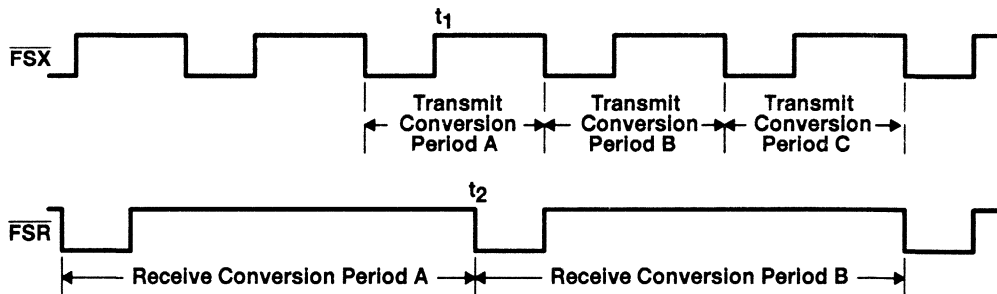


Figure 2-6. More Than One Transmit Frame Sync Between Two Receive Frame Syncs

2.23 More than One Set of Primary and Secondary DX Serial Communications Occurring Between Two Receive Frame Syncs (See DX Serial Data Word Format section) – Asynchronous Operation

The TA, TA', TB, and control register information that is transmitted in the secondary communication is accepted and applied during the ongoing transmit conversion period. If there is sufficient time between t_1 and t_2 , the TA, RA', and RB register information, sent during transmit conversion period A, is applied to receive conversion period A; otherwise, this information is applied during receive conversion period B. If RA, RA', and RB register information has been received and is being applied during an ongoing conversion period, any subsequent RA, RA', or RB information received during this receive conversion period is disregarded (see Figure 2-7).

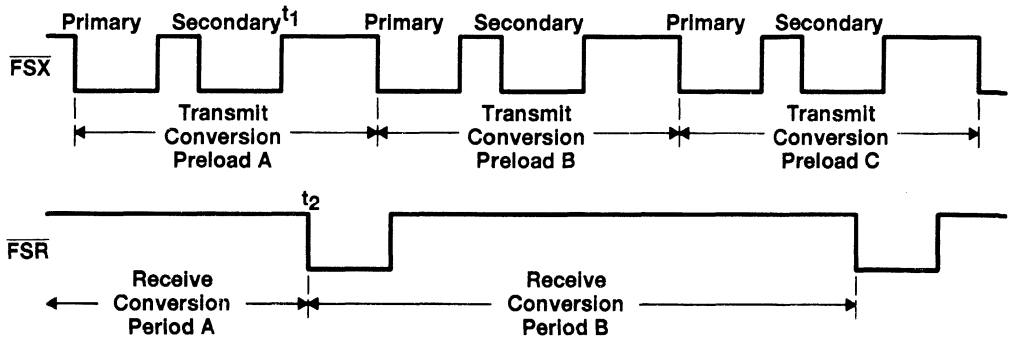


Figure 2–7. More Than One Set of Primary and Secondary DX Serial Communications Between Two Receive Frame Syncs

2.24 System Frequency Response Correction

The $(\sin x)/x$ correction for the DAC zero-order sample-and-hold output can be provided by an on-board second-order $(\sin x)/x$ correction filter (see Functional Block Diagram). This $(\sin x)/x$ correction filter can be inserted into or omitted from the signal path by digital-signal-processor control (data bit D9 in the DX secondary communications). When inserted, the $(\sin x)/x$ correction filter precedes the switched-capacitor low-pass filter. When the TB register (see Figure 2–1) equals 15, the correction results of Figures 5–5, 5–6, and 5–7 can be obtained.

The $(\sin x)/x$ correction [see section $(\sin x)/x$] can also be accomplished by disabling the on-board second-order correction filter and performing the $(\sin x)/x$ correction in digital signal processor software. The system frequency response can be corrected via DSP software to ± 0.1 dB accuracy to a band edge of 3000 Hz for all sampling rates. This correction is accomplished with a first-order digital correction filter, that requires seven TMS320 instruction cycles. With a 200-ns instruction cycle, seven instructions represent an overhead factor of 1.1% and 1.3% for sampling rates of 8 and 9.6 kHz, respectively (see the $(\sin x)/x$ Correction Section for more details).

2.25 $(\sin x)/x$ Correction

If the designer does not wish to use the on-board second-order $(\sin x)/x$ correction filter, correction can be accomplished in digital signal processor (DSP) software. $(\sin x)/x$ correction can be accomplished easily and efficiently in digital signal processor software. Excellent correction accuracy can be achieved to a band edge of 3000 Hz by using a first-order digital correction filter. The results shown are typical of the numerical correction accuracy that can be achieved for sample rates of interest. The filter requires seven instruction cycles per sample on the TMS320 DS. With a 200-ns instruction cycle, nine instructions per sample represents an overhead factor of 1.4% and 1.7% for sampling rates of 8000 Hz and 9600 Hz, respectively. This correction adds a slight amount of group delay at the upper edge of the 300-Hz to 3000-Hz band.

2.26 $(\sin x)/x$ Roll-Off for a Zero-Order Hold Function

The $(\sin x)/x$ roll-off error for the AIC DAC zero-order hold function at a band-edge frequency of 3000 Hz for the various sampling rates is shown in Table 2–5 (see Figure 5–7).

Table 2-5. (sin x)/x Roll-Off Error

f_s (Hz)	Error = $20 \log \frac{\sin \pi f/f_s}{\pi f/f_s}$ $f = 3000$ Hz (dB)
7200	-2.64
8000	-2.11
9600	-1.44
14400	-0.63
16000	-0.50
19200	-0.35
25000	-0.21

The actual AIC (sin x)/x roll-off is slightly less than the figures in Table 2-5 because the AIC has less than 100% duty cycle hold interval.

2.27 Correction Filter

To externally compensate for the (sin x)/x roll-off of the AIC, a first-order correction filter can be implemented as shown in Figure 2-8.

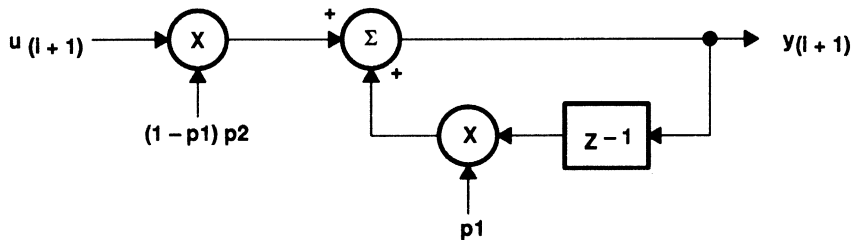


Figure 2-8. First-Order Correction Filter

The difference equation for this correction filter is:

$$y(i+1) = p_2 \cdot (1-p_1) \cdot u(i+1) + p_1 \cdot y(i) \quad (4)$$

where the constant p_1 determines the pole locations.

The resulting squared magnitude transfer function is:

$$|H(f)|^2 = \frac{(p_2)^2 V (1-p_1)^2}{1-2 V p_1 V \cos(2\pi f/f_s) + (p_1)^2} \quad (5)$$

2.28 Correction Results

Table 2-6 shows the optimum p values and the corresponding correction results for 8000-Hz and 9600-Hz sampling rates (see Figures 5-8, 5-9, and 5-10).

Table 2–6. (Sin x)/x Correction Table for $f_s = 8000$ Hz and $f_s = 9600$ Hz

f (Hz)	ROLL-OFF ERROR (dB)	ROLL-OFF ERROR (dB)
	$f_s = 8000$ Hz p1 = -0.14813 p2 = 0.9888	$f_s = 9600$ Hz p1 = -0.1307 p2 = 0.9951
300	-0.099	-0.043
600	-0.089	-0.043
900	-0.054	0
1200	-0.002	0
1500	0.041	0
1800	0.079	0.043
2100	0.100	0.043
2400	0.091	0.043
2700	-0.043	0
3000	-0.102	-0.043

2.29 TMS320 Software Requirements

The digital correction filter equation can be written in state variable form as follows:

$$y_{(i+1)} = y_{(i)} \cdot k1 + u_{(i+1)} \cdot k2$$

Where

$$k1 = p1$$

$$k2 = (1 - p1) p2$$

$y(i)$ = filter state

$u(i+1)$ = next I/O sample

The coefficients $k1$ and $k2$ must be represented as 16-bit integers. The SACH instruction (with the proper shift) yields the correct result. With the assumption that the TMS320 processor page pointer and memory configuration are properly initialized, the equation can be executed in seven instructions or seven cycles with the following program:

```
ZAC
LT K2
MPY U
LTA K1
MPY Y
APAC
SACH (dma), (shift)
```

3 Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (Unless Otherwise Noted)

Supply voltage range, V_{CC+} (see Note 1)	-0.3 V to 15 V
Supply voltage range, V_{DD}	-0.3 V to 15 V
Output voltage range, V_O	-0.3 V to 15 V
Input voltage range, V_I	-0.3 V to 15 V
Digital ground voltage range	-0.3 V to 15 V
Operating free-air temperature range: TLC32046C	0°C to 70°C
TLC32046I	-40°C to 85°C
TLC32046M	-55°C to 125°C
Storage temperature range: TLC32046C, TLC32046I	-40°C to 125°C
TLC32046M	-65°C to 150°C
Case temperature for 10 seconds: FN or FK package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds:		
N or J package	260°C

NOTE 1: Voltage values for maximum ratings are with respect to V_{CC-} .

3.2 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+} (see Note 2)	4.75	5	5.25	V
Supply voltage, V_{CC-} (see Note 2)	-4.75	-5	-5.25	V
Digital supply voltage, V_{DD} (see Note 2)	4.75	5	5.25	V
Digital ground voltage with respect to ANLG GND, DGTL GND		0		V
Reference input voltage, $V_{ref(ext)}$ (see Note 2)	2		4	V
High-level input voltage, V_{IH}	2		$V_{DD}+0.3$	V
Low-level input voltage, V_{IL} (see Note 3)	-0.3		0.8	V
Load resistance at OUT+ and/or OUT-, R_L	300			Ω
Load capacitance at OUT+ and/or OUT-, C_L			100	pF
MSTR CLK frequency (see Note 4)		5	10.368	MHz
Analog input amplifier common mode input voltage (see Note 5)			± 1.5	V
A/D or D/A conversion rate			25	kHz
Operating free-air temperature range, T_A	TLC32046C	0	70	°C
	TLC32046I	-40	85	
	TLC32046M	-55	125	

NOTES: 2. Voltages at analog inputs and outputs, REF, V_{CC+} , and V_{CC-} are with respect to ANLG GND. Voltages at digital inputs and outputs and V_{DD} are with respect to DGTL GND.

3. The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data manual for logic voltage levels only.
4. The band-pass switched-capacitor filter (SCF) specifications apply only when the low-pass section SCF clock is 288 kHz and the high-pass section SCF clock is 16 kHz. If the low-pass SCF clock is shifted from 288 kHz, the low-pass roll-off frequency shifts by the ratio of the low-pass SCF clock to 288 kHz. If the high-pass SCF clock is shifted from 16 kHz, the high-pass roll-off frequency shifts by the ratio of the high-pass SCF clock to 16 kHz. Similarly, the low-pass switched-capacitor filter (SCF) specifications apply only when the SCF clock is 288 kHz. If the SCF clock is shifted from 288 kHz, the low-pass roll-off frequency shifts by the ratio of the SCF clock to 288 kHz.
5. This range applies when $(IN+ - IN-)$ or $(AUX IN+ - AUX IN-)$ equals ± 6 V.

3.3 Electrical Characteristics Over Recommended Operating Free-Air Temperature Range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted)

3.3.1 Total Device, MSTR CLK Frequency = 5.184 MHz, Outputs Not Loaded

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$V_{DD} = 4.75\text{ V}$, $I_{OH} = -300\text{ }\mu\text{A}$	2.4			V
V_{OL}	Low-level output voltage	$V_{DD} = 4.75\text{ V}$, $I_{OL} = 2\text{ mA}$			0.4	V
I_{CC+}	Supply current from V_{CC+}	TLC32046C			35	mA
		TLC32046I			40	
		TLC32046M			45	
I_{CC-}	Supply current from V_{CC-}	TLC32046C			-35	mA
		TLC32046I			-40	
		TLC32046M			-45	
I_{DD}	Supply current from V_{DD}				7	mA
V_{ref}	Internal reference output voltage	TLC32046M	2.9		3.3	V
αV_{ref}	Temperature coefficient of internal reference voltage			250		ppm/°C
r_o	Output resistance at REF			100		k Ω

3.3.2 Power Supply Rejection and Crosstalk Attenuation

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{CC+} or V_{CC-} supply voltage rejection ratio, receive channel	$f = 0\text{ kHz to }30\text{ kHz}$	Idle channel, supply signal at 200 mV p-p measured at DR (ADC output)		30		dB
	$f = 30\text{ kHz to }50\text{ kHz}$			45		
V_{CC+} or V_{CC-} supply voltage rejection ratio, transmit channel (single-ended)	$f = 0\text{ kHz to }30\text{ kHz}$	Idle channel, supply signal at 200 mV p-p measured at OUT +		30		dB
	$f = 30\text{ kHz to }50\text{ kHz}$			45		
Crosstalk attenuation, transmit-to-receive (single-ended)	TLC32046C, I			80		dB
	TLC32046M		60	80		
Crosstalk attenuation, receive-to-transmit (single-ended)	TLC32046M		70	80		dB

3.3.3 Serial Port

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$I_{OH} = -300\text{ }\mu\text{A}$	2.4			V
V_{OL}	Low-level output voltage	$I_{OL} = 2\text{ mA}$			0.4	V
I_I	Input current				± 10	μA
I_I	Input current, DATA-DR/CONTROL				± 100	μA
C_i	Input capacitance			15		pF
C_o	Output capacitance			15		pF

† All typical values are at $T_A = 25^\circ\text{C}$.

3.3.4 Receive Amplifier Input

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
A/D converter offset error (filters in)				10	70	mV
CMRR	Common-mode rejection ratio at IN+, IN–, or AUX IN+, AUX IN–	See Note 6		55		dB
r_i	Input resistance at IN+, IN– or AUX IN+, AUX IN+, AUX IN–, REF			100		k Ω

NOTE 6: The test condition is a 0-dBm, 1-kHz input signal with a 16-kHz conversion rate.

3.3.5 Transmit Filter Output

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OO}	Output offset voltage at OUT+ or OUT– (single-ended relative to ANLG GND)	TLC32046C, I		15	80	mV
		TLC32046M		15	85	mV
V_{OM}	Maximum peak output voltage swing across R_L at OUT+ or OUT– (single-ended)	TLC32046C, I	$R_L \geq 300 \Omega$, Offset voltage = 0	± 3		V
	Maximum peak output voltage swing between OUT+ and OUT– (differential output)					

† All typical values are at $T_A = 25^\circ\text{C}$.

3.3.6 Receive and Transmit Channel System Distortion, SCF Clock Frequency = 288kHz (see Note 7)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Attenuation of second harmonic of A/D input signal	Single-ended	$V_I = -0.1 \text{ dB to } -24 \text{ dB}$			70	dB
	Differential		62	70		
Attenuation of third and higher harmonics of A/D input signal	Single-ended				65	dB
	Differential		57	65		
Attenuation of second harmonic of D/A input signal	Single-ended	$V_I = -0 \text{ dB to } -24 \text{ dB}$			70	dB
	Differential		62	70		
Attenuation of third and higher harmonics of D/A input signal	Single-ended				65	dB
	Differential		57	65		

† All typical values are at $T_A = 25^\circ\text{C}$.

3.3.7 Receive Channel Signal-to-Distortion Ratio (see Note 7)

PARAMETER	TEST CONDITIONS	$A_V = 1\ddagger$		$A_V = 2\ddagger$		$A_V = 4\ddagger$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
A/D channel signal-to-distortion ratio	$V_I = -6 \text{ dB to } -0.1 \text{ dB}$	58		§		§		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	58		58		§		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	56		58		58		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	50		56		58		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	44		50		56		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	38		44		50		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	32		38		44		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	26		32		38		
	$V_I = -54 \text{ dB to } -48 \text{ dB}$	20		26		32		

‡ A_V is the programmable gain of the input amplifier.

§ Measurements under these conditions are unreliable due to overrange and signal clipping.

NOTE 7: The test condition is a 1-kHz input signal with a 16-kHz conversion rate. The load impedance for the DAC is 600 Ω . Input and output voltages are referred to V_{ref} .

3.3.8 Transmit Channel Signal-to-Distortion Ratio (see Note 7)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
D/A channel signal-to-distortion ratio	$V_I = -6 \text{ dB to } -0.1 \text{ dB}$	58		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	58		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	56		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	50		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	44		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	38		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	32		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	26		
	$V_I = -54 \text{ dB to } -48 \text{ dB}$	20		

NOTE 7: The test condition is a 1-kHz input signal with a 16-kHz conversion rate. The load impedance for the DAC is 600 Ω . Input and output voltages are referred to V_{ref} .

3.3.9 Receive and Transmit Gain and Dynamic Range (see Note 8)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Transmit gain tracking error	C, I $V_O = -48 \text{ dB to } 0 \text{ dB signal range}$		± 0.05	± 0.15	dB
Receive gain tracking error	C, I $V_I = -48 \text{ dB to } 0 \text{ dB signal range}$		± 0.05	± 0.15	dB
Transmit gain tracking error	M $V_O = -48 \text{ dB to } 0 \text{ dB signal range, } T_A = 25^\circ\text{C}$		± 0.05	± 0.25	dB
Receive gain tracking error	M $V_I = -48 \text{ dB to } 0 \text{ dB signal range, } T_A = 25^\circ\text{C}$		± 0.05	± 0.25	dB
Transmit gain tracking error	M $V_O = -48 \text{ dB to } 0 \text{ dB signal range, } T_A = -55^\circ\text{C TO } 125^\circ\text{C}$			± 0.4	dB
Receive gain tracking error	M $V_I = -48 \text{ dB to } 0 \text{ dB signal range, } T_A = -55^\circ\text{C TO } 125^\circ\text{C}$			± 0.4	dB

NOTE 8: Gain tracking is relative to the absolute gain at 1 kHz and 0 dB (0 dB relative to V_{ref}).

3.3.10 Receive Channel Band-Pass Filter Transfer Function, SCF $f_{\text{clock}} = 288$ kHz, Input (IN+ – IN–) Is A ± 3 -V Sine Wave‡ (see Note 9)

PARAMETER	TEST CONDITION	FREQUENCY	ADJUSTMENT	MIN	TYP†	MAX	UNIT
Filter gain	Input signal reference is 0 dB	$f \leq 100$ Hz	$K1 \times 0$ dB	-33	-29	-25	dB
		$f = 200$ Hz	$K1 \times -0.26$ dB	-4	-2	-1	
		$f = 300$ Hz to 6200 Hz	$K1 \times 0$ dB	-0.25	0	0.25	
		$f = 6200$ Hz to 6600 Hz	$K1 \times 0$ dB	-0.3	0	0.3	
		$f = 6600$ Hz to 7300 Hz	$K1 \times 0$ dB		0	0.5	
		$f = 7600$ Hz	$K1 \times 2.3$ dB		-2	-0.5	
		$f = 8000$ Hz	$K1 \times 2.7$ dB		-16	-14	
		$f \geq 8800$ Hz	$K1 \times 3.2$ dB			-40	
		$f \geq 10000$ Hz	$K1 \times 0$ dB			-65	

3.3.11 Receive and Transmit Channel Low-Pass Filter Transfer Function, SCF $f_{\text{clock}} = 288$ kHz (see Note 9)

	TEST CONDITION	FREQUENCY RANGE	ADJUSTMENT ADDEND‡	MIN	TYP†	MAX	UNIT
Filter gain	Input signal reference is 0 dB	$f = 0$ Hz to 6200 Hz	$K1 \times 0$ dB	-0.25	0	0.25	dB
		$f = 6200$ Hz to 6600 Hz	$K1 \times 0$ dB	-0.3	0	0.3	
		$f = 6600$ Hz to 7300 Hz	$K1 \times 0$ dB	-0.5	0	0.5	
		$f = 7600$ Hz	$K1 \times 2.3$ dB		-2	-0.5	
		$f = 8000$ Hz	$K1 \times 2.7$ dB		-16	-14	
		$f \geq 8800$ Hz	$K1 \times 3.2$ dB			-40	
		$f \geq 10000$ Hz	$K1 \times 0$ dB			-65	

† All typical values are at $T_A = 25^\circ\text{C}$.

‡ The MIN, TYP, and MAX specifications are given for a 288-kHz SCF clock frequency. A slight error in the 288-kHz SCF may result from inaccuracies in the MSTR CLK frequency, resulting from crystal frequency tolerances. If this frequency error is less than 0.25%, the ADJUSTMENT ADDEND should be added to the MIN, TYP, and MAX specifications, where $K1 = 100 \cdot [(SCF \text{ frequency} - 288 \text{ kHz})/288 \text{ kHz}]$. For errors greater than 0.25%, see Note 9.

NOTE 9: The filter gain outside of the pass band is measured with respect to the gain at 1 kHz (2 kHz for M version). The filter gain within the pass band is measured with respect to the average gain within the pass band. The pass bands are 300 Hz to 7200 Hz and 0 to 7200 Hz for the band-pass and low-pass filters, respectively. For switched-capacitor filter clocks at frequencies other than 288 kHz, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 288 kHz.

3.4 Operating Characteristics Over Recommended Operating Free-Air Temperature Range, $V_{CC+} = 5\text{ V}$, $V_{CC-} = -5\text{ V}$, $V_{DD} = 5\text{ V}$

3.4.1 Receive and Transmit Noise (measurement includes low-pass and band-pass switched-capacitor filters)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Transmit noise	Broadband with (sin x)/x	DX input = 00000000000000, Constant input code		250	500	μVrms
	Broadband without (sin x)/x			200	450	
	0 to 30 kHz with (sin x)/x			200	400	
	0 to 30 kHz without (sin x)/x			200	400	
	0 to 3.4 kHz with (sin x)/x			180	300	
	0 to 3.4 kHz without (sin x)/x			160	300	
	0 to 6.8 kHz with (sin x)/x (wide-band operation with 7.2 kHz roll-off)			180	350	
	0 to 6.8 kHz without (sin x)/x (wide-band operation with 7.2 kHz roll-off)			160	350	
Receive noise (see Note 10)		Inputs grounded, Gain = 1		300	500	μVrms
				18		dBrnc0

† All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 10: The noise is computed by statistically evaluating the digital output of the A/D converter.

3.5 Timing Requirements

3.5.1 Serial Port Recommended Input Signals, TLC32046C and TLC32046I

PARAMETER		MIN	MAX	UNIT
$t_c(\text{MCLK})$	Master clock cycle time	95		ns
$t_r(\text{MCLK})$	Master clock rise time		10	ns
$t_f(\text{MCLK})$	Master clock fall time		10	ns
	Master clock duty cycle	25%	75%	
	$\overline{\text{RESET}}$ pulse duration (see Note 11)	800		ns
$t_{su}(\text{DX})$	DX setup time before SCLK↓	20		ns
$t_h(\text{DX})$	DX hold time after SCLK↓		$t_c(\text{SCLK})/4$	ns

NOTE 11: $\overline{\text{RESET}}$ pulse duration is the amount of time that the $\overline{\text{RESET}}$ is held below 0.8 V after the power supplies have reached their recommended values.

3.5.2 Serial Port Recommended Input Signals, TLC32046M

PARAMETER		MIN	TYP†	MAX	UNIT
$t_c(\text{MCLK})$	Master clock cycle time	95			ns
$t_r(\text{MCLK})$	Master clock rise time		10		ns
$t_f(\text{MCLK})$	Master clock fall time		10		ns
	Master clock duty cycle		50%		
	$\overline{\text{RESET}}$ pulse duration (see Note 11)	800			ns
$t_{su}(\text{DX})$	DX setup time before SCLK↓	28			ns
$t_h(\text{DX})$	DX hold time after SCLK↓		$t_c(\text{SCLK})/4$		ns

NOTE 11: $\overline{\text{RESET}}$ pulse duration is the amount of time that the $\overline{\text{RESET}}$ is held below 0.8 V after the power supplies have reached their recommended values.

3.5.3 Serial Port – AIC Output Signals, $C_L = 30$ pF for SHIFT CLK Output, $C_L = 15$ pF For All Other Outputs, TLC32046C and TLC32046I

PARAMETER		MIN	TYP†	MAX	UNIT
t_c (SCLK)	Shift clock (SCLK) cycle time	380			ns
t_f (SCLK)	Shift clock (SCLK) fall time		3	8	ns
t_r (SCLK)	Shift clock (SCLK) rise time		3	8	ns
	Shift clock (SCLK) duty cycle	45%		55%	
t_d (CH-FL)	Delay from SCLK↑ to $\overline{FSR}/\overline{FSX}/\overline{FSD}\downarrow$		30		ns
t_d (CH-FH)	Delay from SCLK↑ to $\overline{FSR}/\overline{FSX}/\overline{FSD}\uparrow$		35	90	ns
t_d (CH-DR)	DR valid after SCLK↑			90	ns
t_d (CH-EL)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\downarrow$ in word mode			90	ns
t_d (CH-EH)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\uparrow$ in word mode			90	ns
t_f (EODX)	\overline{EODX} fall time		2	8	ns
t_f (EODR)	\overline{EODR} fall time		2	8	ns
t_d (CH-EL)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\downarrow$ in byte mode			90	ns
t_d (CH-EH)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\uparrow$ in byte mode			90	ns
t_d (MH-SL)	Delay from MSTR CLK↑ to SCLK↓		65	170	ns
t_d (MH-SH)	Delay from MSTR CLK↑ to SCLK↑		65	170	ns

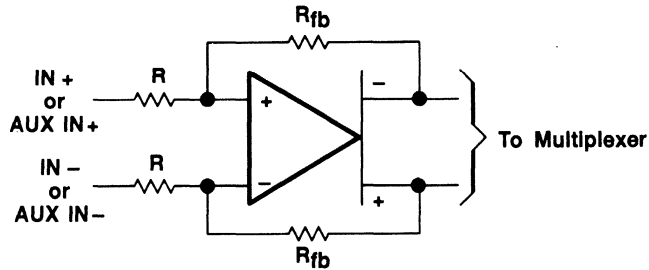
† Typical values are at $T_A = 25^\circ\text{C}$.

3.5.4 Serial Port – AIC Output Signals, $C_L = 30$ pF for SHIFT CLK Output, $C_L = 15$ pF For All Other Outputs, TLC32046M

PARAMETER		MIN	TYP†	MAX	UNIT
t_c (SCLK)	Shift clock (SCLK) cycle time	400			ns
t_f (SCLK)	Shift clock (SCLK) fall time		3		ns
t_r (SCLK)	Shift clock (SCLK) rise time		3		ns
	Shift clock (SCLK) duty cycle	45%		55%	
t_d (CH-FL)	Delay from SCLK↑ to $\overline{FSR}/\overline{FSX}/\overline{FSD}\downarrow$		30	250	ns
t_d (CH-FH)	Delay from SCLK↑ to $\overline{FSR}/\overline{FSX}/\overline{FSD}\uparrow$		35	250	ns
t_d (CH-DR)	DR valid after SCLK↑			250	ns
t_d (CH-EL)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\downarrow$ in word mode			250	ns
t_d (CH-EH)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\uparrow$ in word mode			250	ns
t_f (EODX)	\overline{EODX} fall time		2		ns
t_f (EODR)	\overline{EODR} fall time		2		ns
t_d (CH-EL)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\downarrow$ in byte mode			250	ns
t_d (CH-EH)	Delay from SCLK↑ to $\overline{EODX}/\overline{EODR}\uparrow$ in byte mode			250	ns
t_d (MH-SL)	Delay from MSTR CLK↑ to SCLK↓		65	170	ns
t_d (MH-SH)	Delay from MSTR CLK↑ to SCLK↑		65	170	ns

† Typical values are at $T_A = 25^\circ\text{C}$.

4 Parameter Measurement Information



$$R_{fb} = R \text{ for } D6 = 1 \text{ and } D7 = 1$$

$$D6 = 0 \text{ and } D7 = 0$$

$$R_{fb} = 2R \text{ for } D6 = 1 \text{ and } D7 = 0$$

$$R_{fb} = 4R \text{ for } D6 = 0, \text{ and } D7 = 1$$

Figure 4–1. IN+ and IN– Gain Control Circuitry

Table 4–1. Gain Control Table (Analog Input Signal Required for Full-Scale Bipolar A/D Conversion Twos Complement)[†]

INPUT CONFIGURATIONS	CONTROL REGISTER BITS		ANALOG INPUT [‡] §	A/D CONVERSION RESULT
	D6	D7		
Differential configuration Analog input = IN+ – IN– = AUX IN+ – AUX IN–	1	1	$V_{ID} = \pm 6 \text{ V}$	\pm full scale
	0	0	$V_{ID} = \pm 3 \text{ V}$	\pm full scale
	1	0	$V_{ID} = \pm 1.5 \text{ V}$	\pm full scale
Single-ended configuration Analog input = IN+ – ANLG GND = AUX IN+ – ANLG GND	1	1	$V_I = \pm 3 \text{ V}$	\pm half scale
	0	0	$V_I = \pm 3 \text{ V}$	\pm full scale
	1	0	$V_I = \pm 1.5 \text{ V}$	\pm full scale

[†] $V_{CC+} = 5 \text{ V}$, $V_{CC-} = -5 \text{ V}$, $V_{DD} = 5 \text{ V}$

[‡] V_{ID} = Differential Input Voltage, V_I = Input voltage referenced to ground with IN– or AUX IN– connected to GND.

[§] In this example, V_{ref} is assumed to be 3 V. In order to minimize distortion, it is recommended that the analog input not exceed 0.1 dB below full scale.

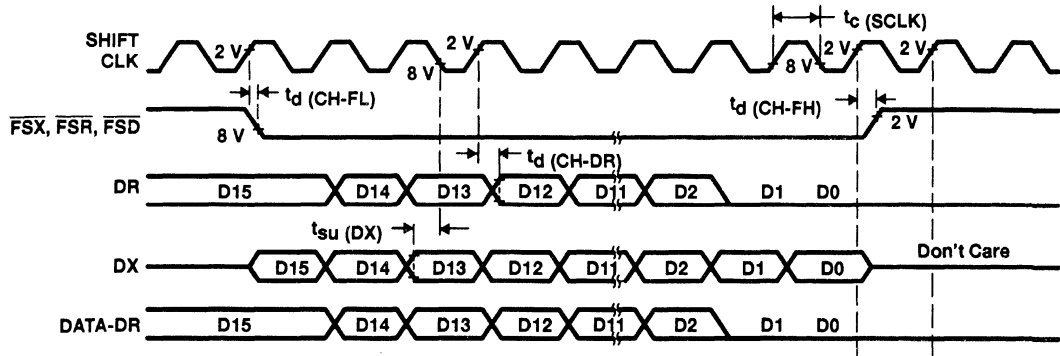


Figure 4-2. Dual-Word (Telephone Interface) Mode Timing

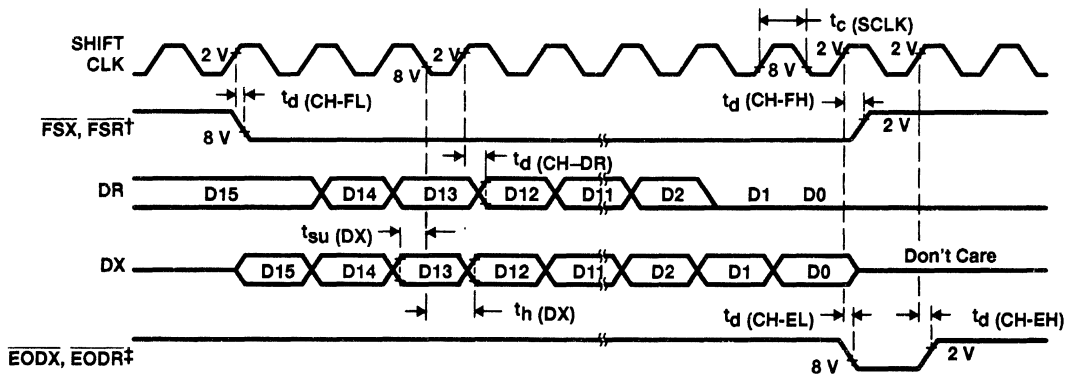


Figure 4-3. Word Timing

† The time between falling edges of \overline{FSR} is the A/D conversion period and the time between falling edges of \overline{FSX} is the D/A conversion period.

‡ In the word format, \overline{EODX} and \overline{EODR} go low to signal the end of a 16-bit data word to the processor. The word-cycle is 20 shift-clocks wide, giving a four-clock period setup time between data words.

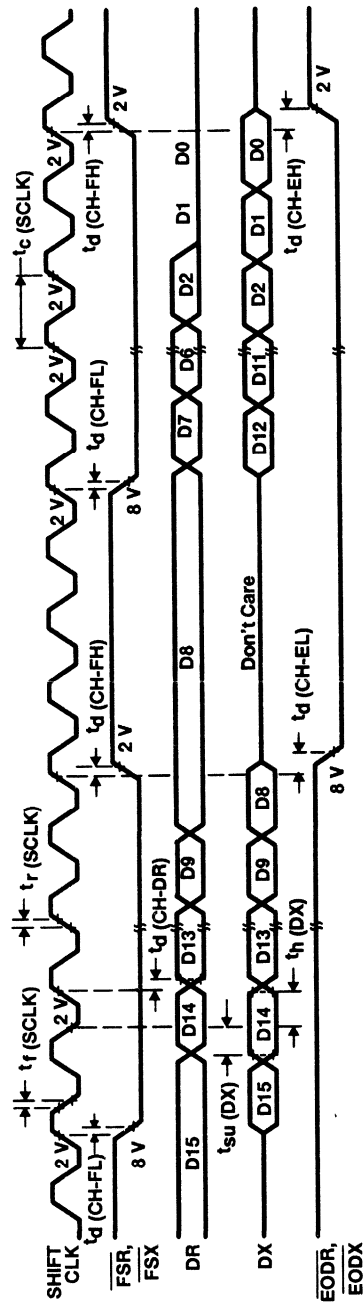


Figure 4-4. Byte-Mode Timing

† The time between falling edges of FSR is the A/D conversion period, and the time between falling edges of FSX is the D/A conversion period.
 ‡ In the byte mode, when EODX or EODR is high, the first byte is transmitted or received, and when these signals are low, the second byte is transmitted or received. Each byte-cycle is 12 shift-clocks long, allowing for a four-shift-clock setup time between byte transmissions.

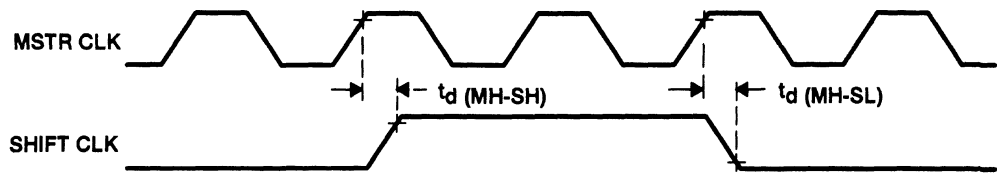


Figure 4-5. Shift-Clock Timing

4.1 TMS32010/TMS320C15 – TLC32046 Interface Circuit

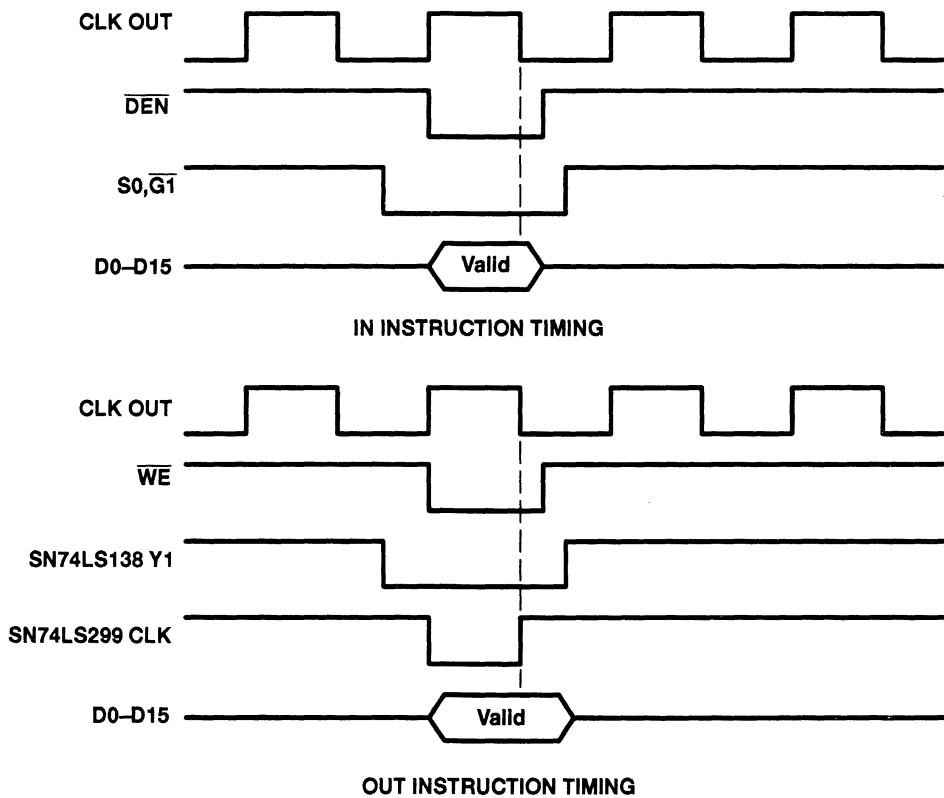


Figure 4-6. TMS32010/TMS320C15 – TLC32046 Interface Timing

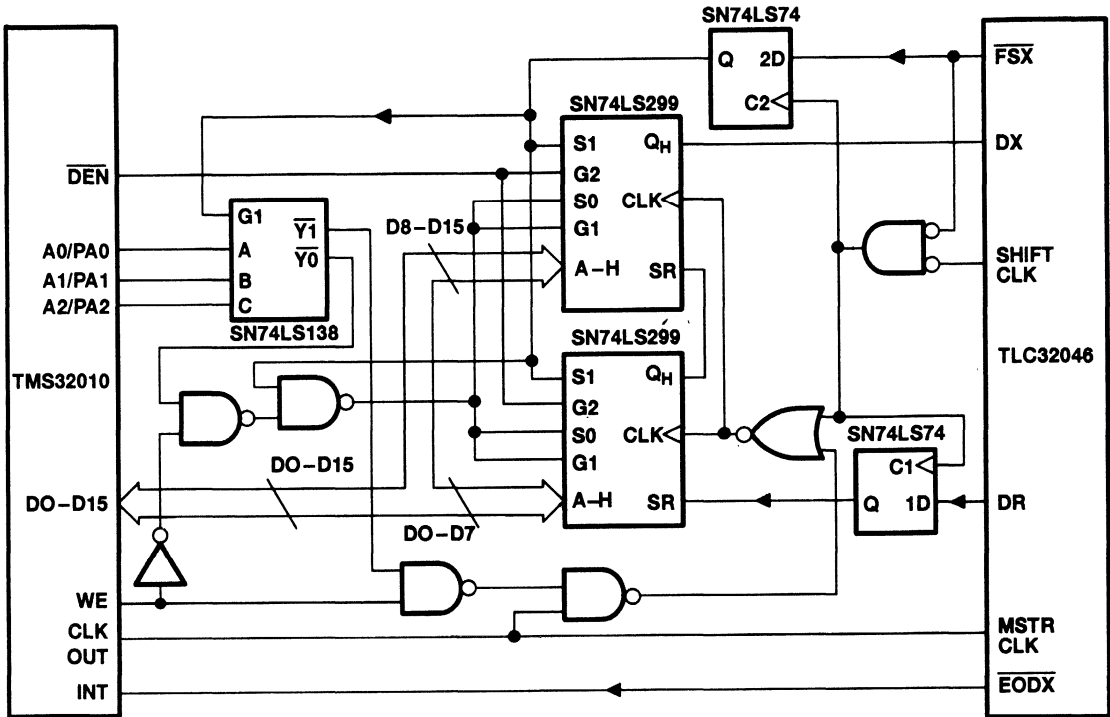


Figure 4-7. TMS32010/TMS320C15 - TLC32046 Interface Circuit

5 Typical Characteristics

D/A AND A/D LOW-PASS FILTER RESPONSE SIMULATION

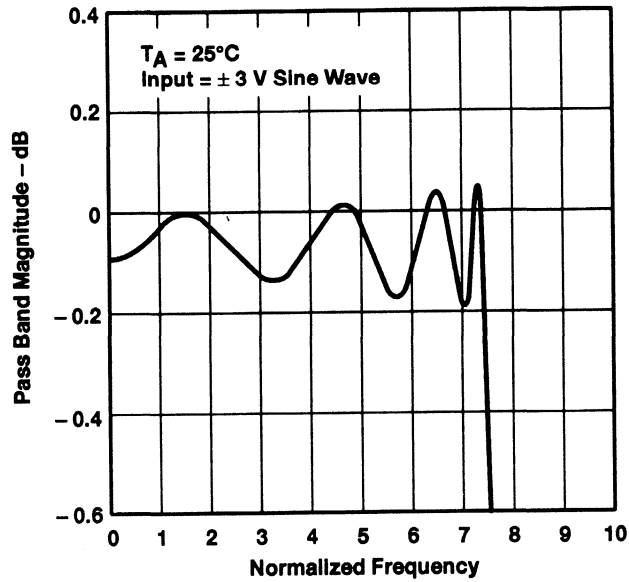


Figure 5-1

D/A AND A/D LOW-PASS FILTER RESPONSE

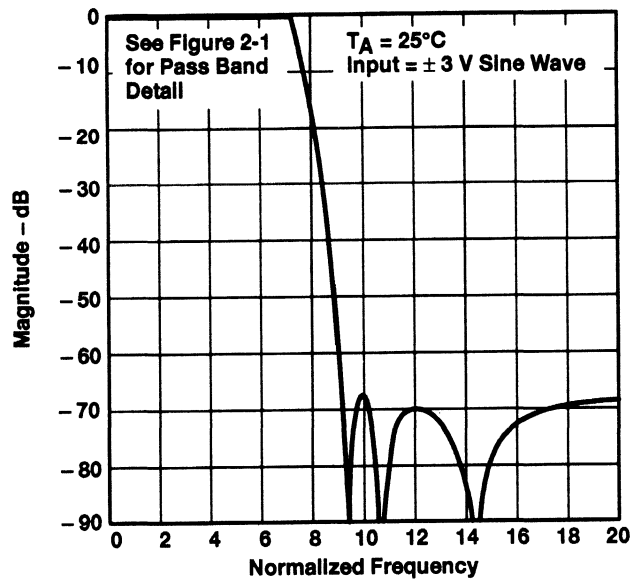


Figure 5-2

NOTE : Absolute Frequency (kHz) =
$$\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{288}$$

For Low-Pass SCF $f_{\text{clock}} > 288$ kHz, please call the factory.

D/A AND A/D LOW-PASS GROUP DELAY

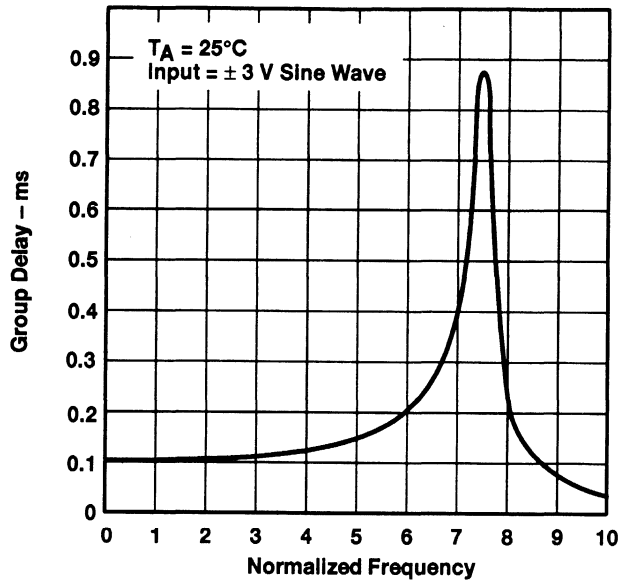


Figure 5-3

A/D BAND-PASS RESPONSE

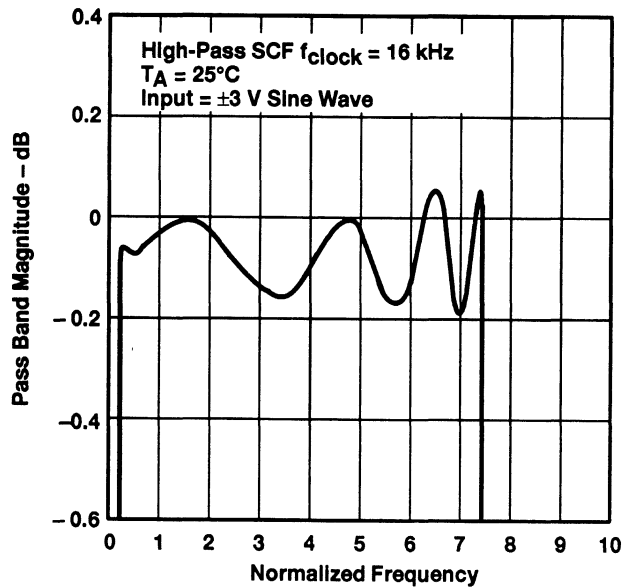


Figure 5-4

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{288}$
 For Low-Pass SCF $f_{\text{clock}} > 288\text{ kHz}$, please call the factory.

A/D BAND-PASS FILTER RESPONSE SIMULATION

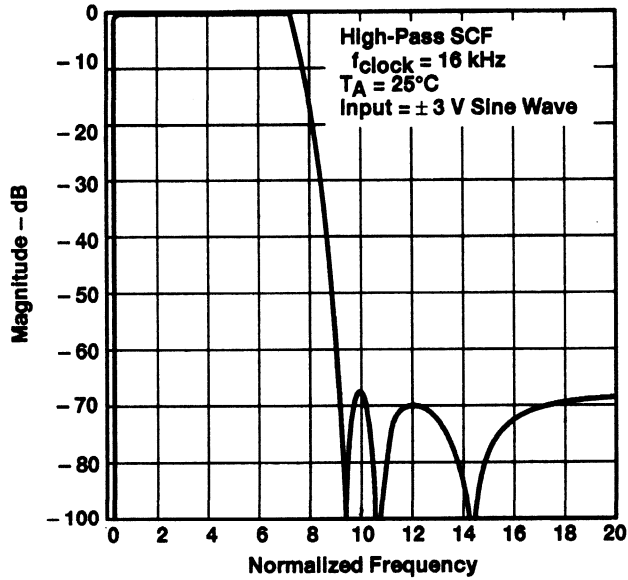


Figure 5-5

A/D BAND-PASS FILTER GROUP DELAY

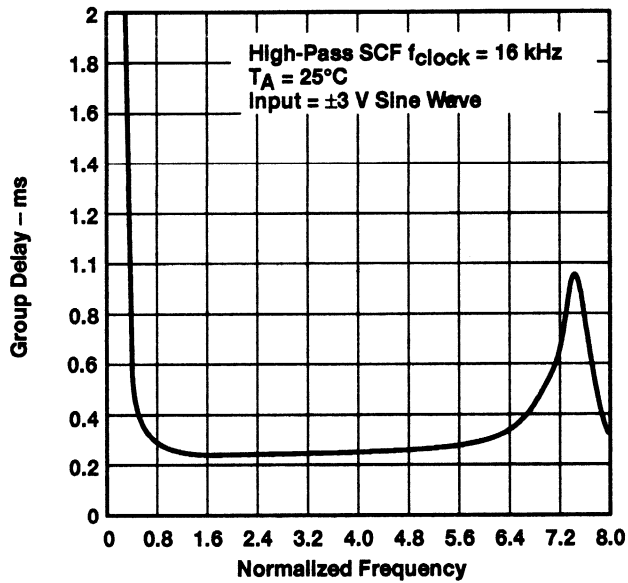


Figure 5-6

NOTE : Absolute Frequency (kHz) =
$$\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{288}$$

For Low-Pass SCF $f_{\text{clock}} > 288$ kHz, please call the factory.

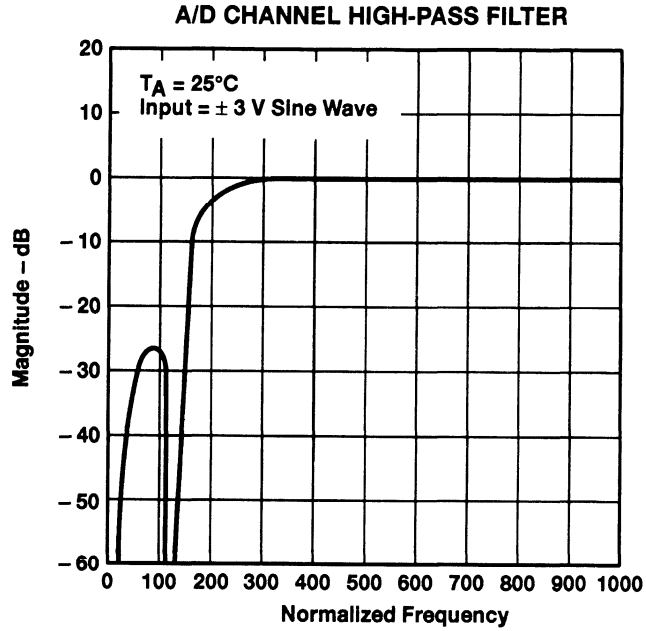


Figure 5-7

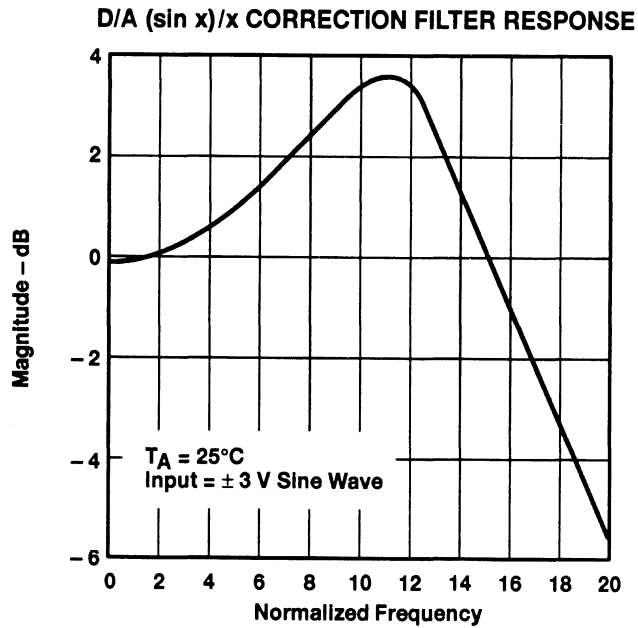


Figure 5-8

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{288}$

For Low-Pass SCF $f_{\text{clock}} > 288$ kHz, please call the factory.

D/A (sin x)/x CORRECTION FILTER RESPONSE

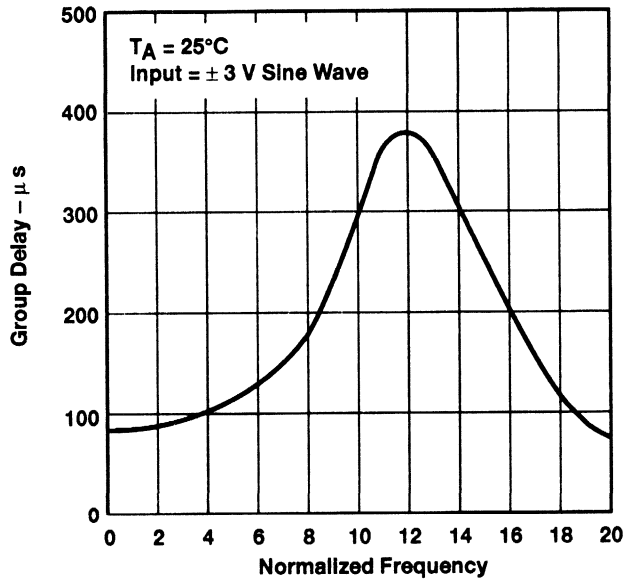


Figure 5-9

D/A (sin x)/x CORRECTION ERROR

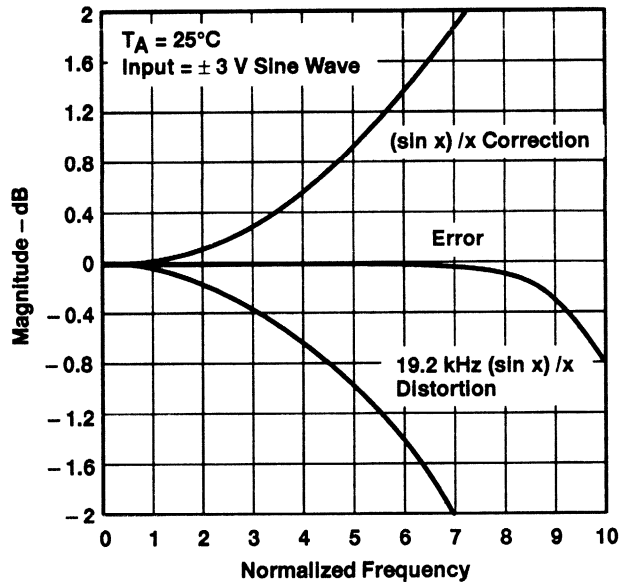


Figure 5-10

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{288}$

For Low-Pass SCF $f_{\text{clock}} > 288\text{ kHz}$, please call the factory.

A/D BAND-PASS GROUP DELAY

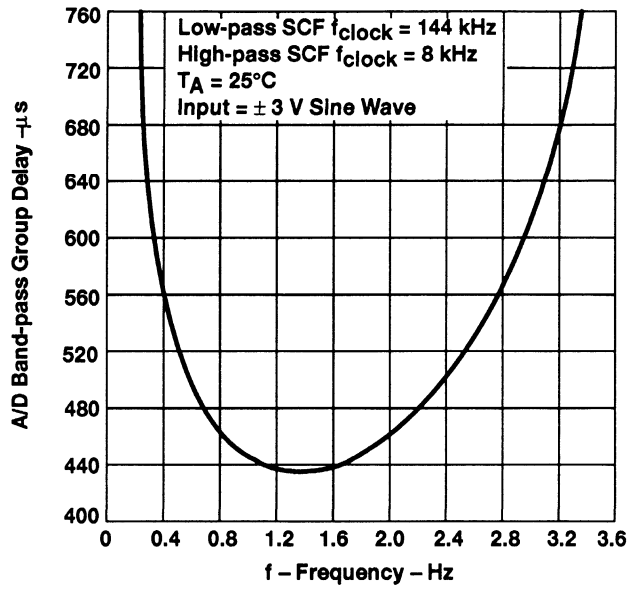


Figure 5-11

D/A LOW-PASS GROUP DELAY

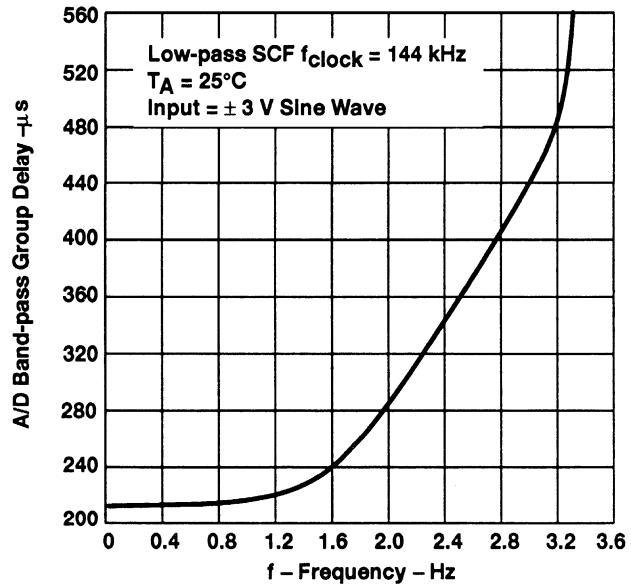


Figure 5-12

**A/D SIGNAL-TO-DISTORTION RATIO
vs
INPUT SIGNAL**

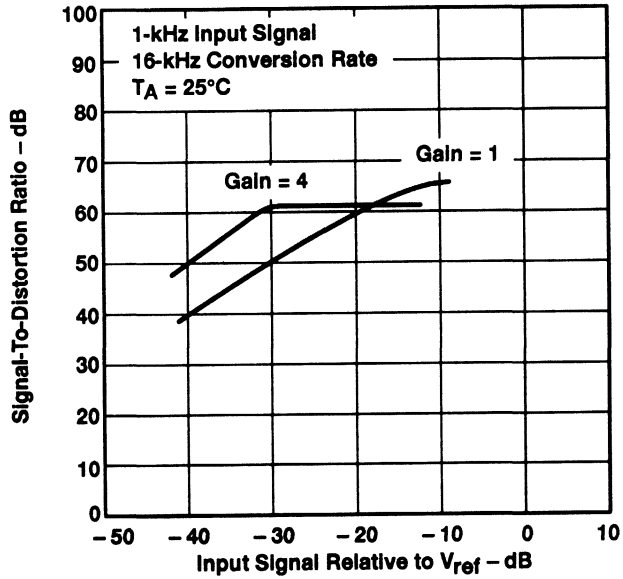


Figure 5-13

**A/D GAIN TRACKING
(GAIN RELATIVE TO GAIN AT 0-dB INPUT SIGNAL)**

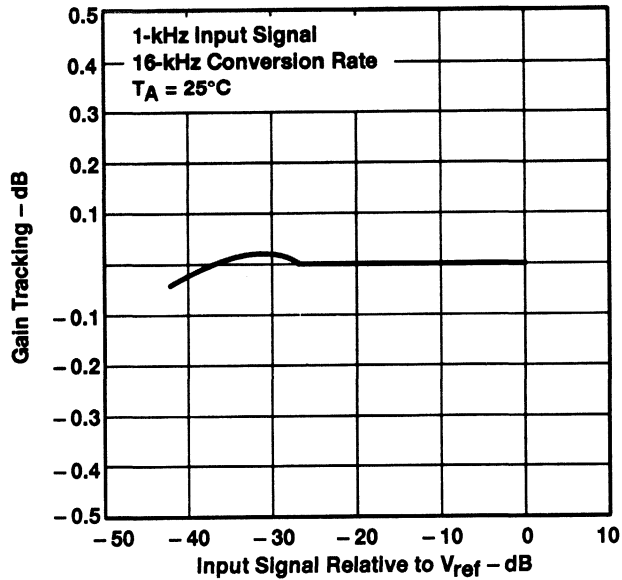


Figure 5-14

**D/A CONVERTER SIGNAL-TO-DISTORTION RATIO
VS
INPUT SIGNAL**

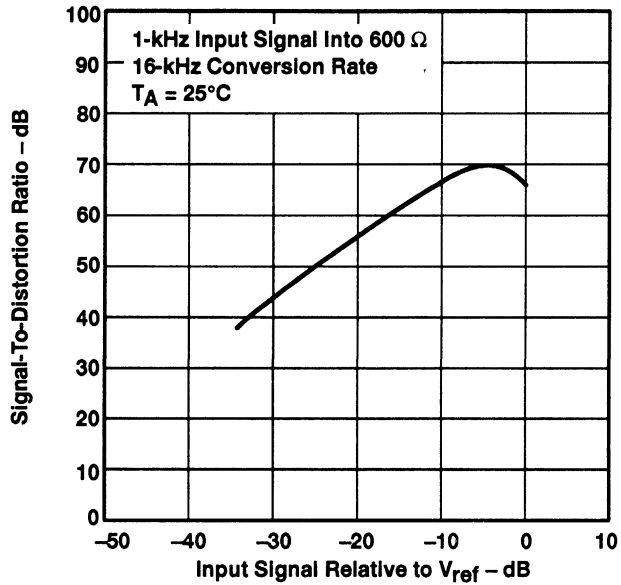


Figure 5-15

**D/A GAIN TRACKING (GAIN RELATIVE TO GAIN
AT 0-dB INPUT SIGNAL)**

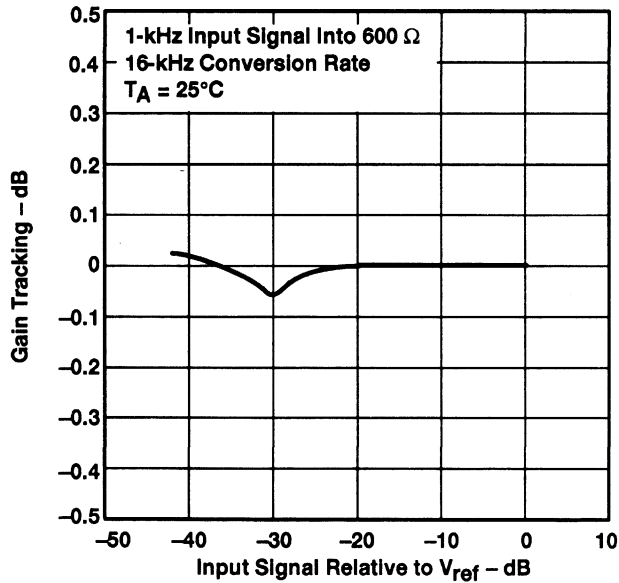


Figure 5-16

**A/D SECOND HARMONIC DISTORTION
vs
INPUT SIGNAL**

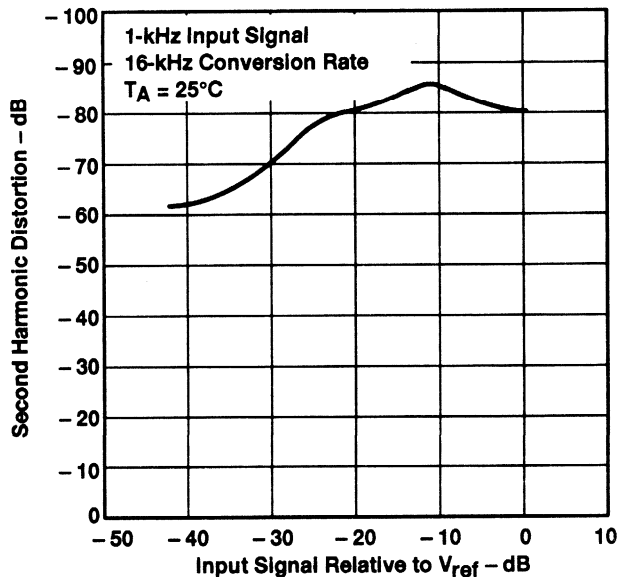


Figure 5-17

**D/A SECOND HARMONIC DISTORTION
vs
INPUT SIGNAL**

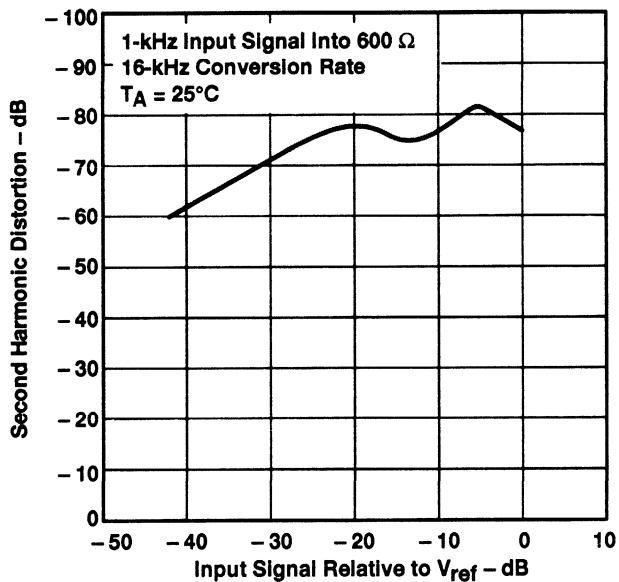


Figure 5-18

**A/D THIRD HARMONIC DISTORTION
vs
INPUT SIGNAL**

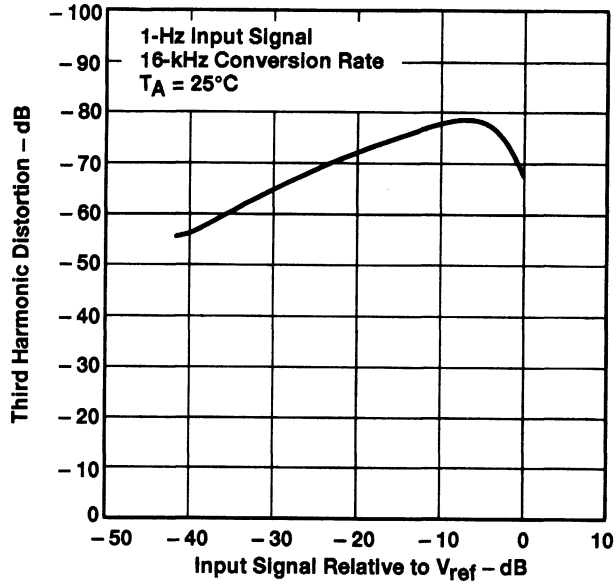


Figure 5-19

**D/A THIRD HARMONIC DISTORTION
vs
INPUT SIGNAL**

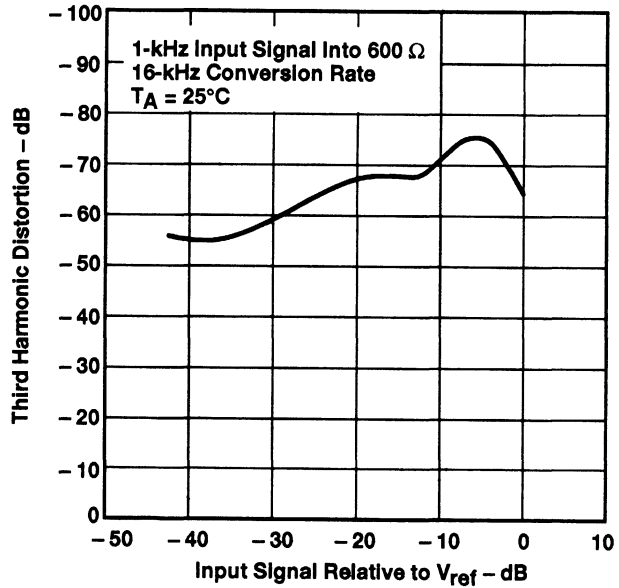


Figure 5-20

6 Application Information

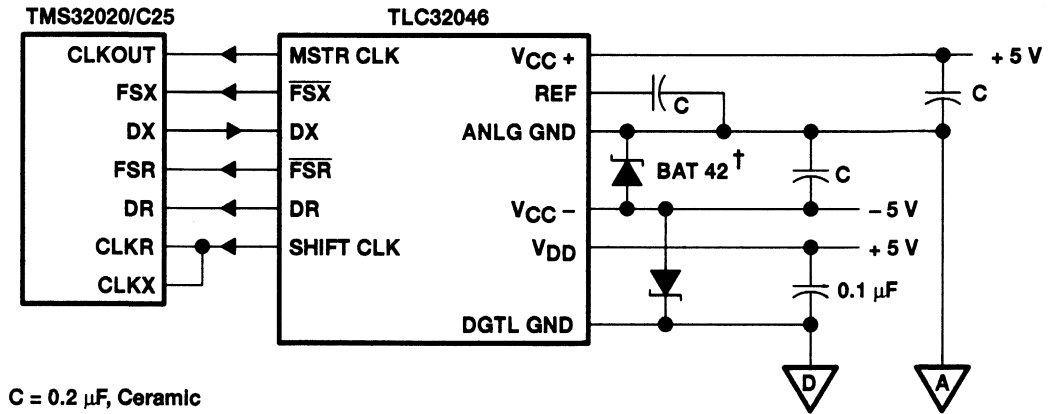
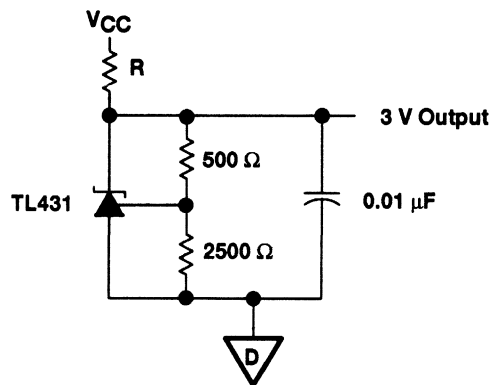


Figure 6-1. AIC Interface to the TMS32020/C25 Showing Decoupling Capacitors and Schottky Diode†

† Thomson Semiconductors



FOR: $V_{CC} = 12 \text{ V}$, $R = 7200 \Omega$
 $V_{CC} = 10 \text{ V}$, $R = 5600 \Omega$
 $V_{CC} = 5 \text{ V}$, $R = 1600 \Omega$

Figure 6-2. External Reference Circuit for TLC32046

TLC32047C, TLC32047I ***Data Manual***

Wide-Band Analog Interface Circuit



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1 Introduction

The TLC32047 wide-band analog interface circuit (AIC) is a complete analog-to-digital and digital-to-analog interface system for advanced digital signal processors (DSPs) similar to the TMS32020, TMS320C25, and TMS320C30. The TLC32047 offers a powerful combination of options under DSP control: three operating modes [dual-word (telephone interface), word, and byte] combined with two word formats (8 bits and 16 bits) and synchronous or asynchronous operation. It provides a high level of flexibility in that conversion and sampling rates, filter bandwidths, input circuitry, receive and transmit gains, and multiplexed analog inputs are under processor control.

This AIC features a

- band-pass switched-capacitor antialiasing input filter
- 14-bit-resolution A/D converter
- 14-bit-resolution D/A converter
- low-pass switched-capacitor output-reconstruction filter

The antialiasing input filter comprises eighth-order and fourth-order CC-type (Chebyshev/elliptic transitional) low-pass and high-pass filters, respectively. The input filter is implemented in switched-capacitor technology and is preceded by a continuous time filter to eliminate any possibility of aliasing caused by sampled data filtering. When low-pass filtering is desired, the high-pass filter can be switched out of the signal path. A selectable auxiliary differential analog input is provided for applications where more than one analog input is required.

The output-reconstruction filter is an eighth-order CC-type (Chebyshev/elliptic transitional low-pass filter) followed by a second-order $(\sin x)/x$ correction filter and is implemented in switched-capacitor technology. This filter is followed by a continuous-time filter to eliminate images of the sample data signal. The on-board $(\sin x)/x$ correction filter can be switched out of the signal path using digital signal processor control.

The A/D and D/A architectures ensure no missing codes and monotonic operation. An internal voltage reference is provided to ease the design task and to provide complete control over the performance of the IC. The internal voltage reference is brought out to REF. Separate analog and digital voltage supplies and ground are provided to minimize noise and ensure a wide dynamic range. The analog circuit path contains only differential circuitry to keep noise to a minimum. The exception is the DAC sample-and-hold, which utilizes pseudo-differential circuitry.

The TLC32047C is characterized for operation from 0°C to 70°C, and the TLC32047I is characterized for operation from -40°C to 85°C.

1.1 Features

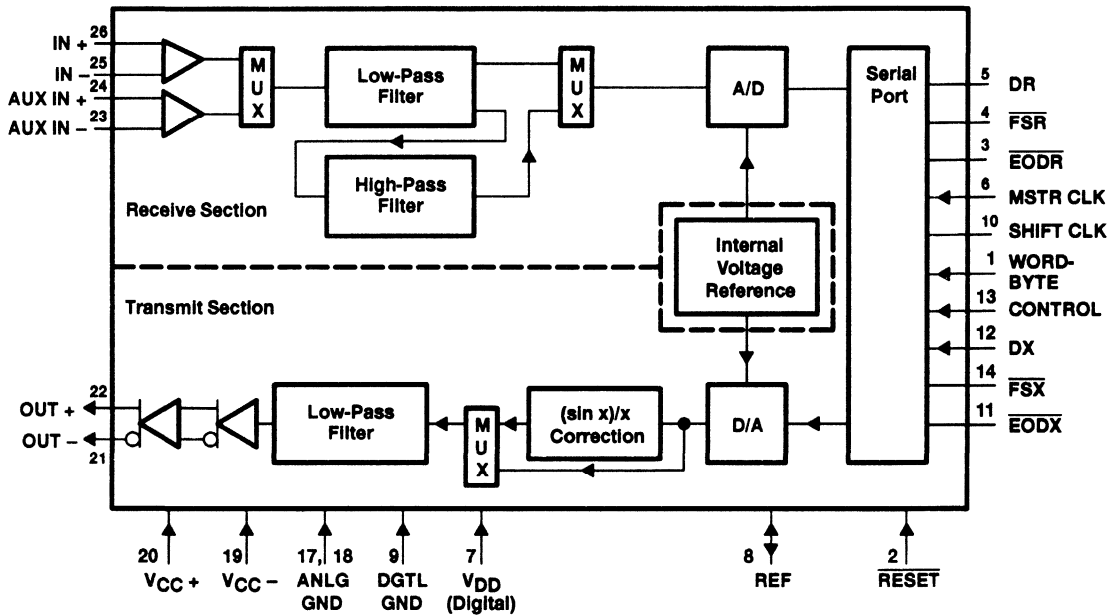
- 14-Bit Dynamic Range ADC and DAC
- 16-Bit Dynamic Range Input With Programmable Gain
- Synchronous or Asynchronous ADC and DAC Sampling Rates Up to 25,000 Samples Per Second
- Programmable Incremental ADC and DAC Conversion Timing Adjustments
- Typical Applications
 - Speech Encryption for Digital Transmission
 - Speech Recognition and Storage Systems
 - Speech Synthesis
 - Modems at 8-kHz, 9.6-kHz, and 16-kHz Sampling Rates
 - Industrial Process Control
 - Biomedical Instrumentation
 - Acoustical Signal Processing
 - Spectral Analysis
 - Instrumentation Recorders
 - Data Acquisition
- Switched-Capacitor Antialiasing Input Filter and Output-Reconstruction Filter
- Three Fundamental Modes of Operation: Dual-Word (Telephone Interface), Word, and Byte
- 600-mil Wide N Package
- Digital Output in Twos Complement Format
- CMOS Technology

FUNCTION TABLE

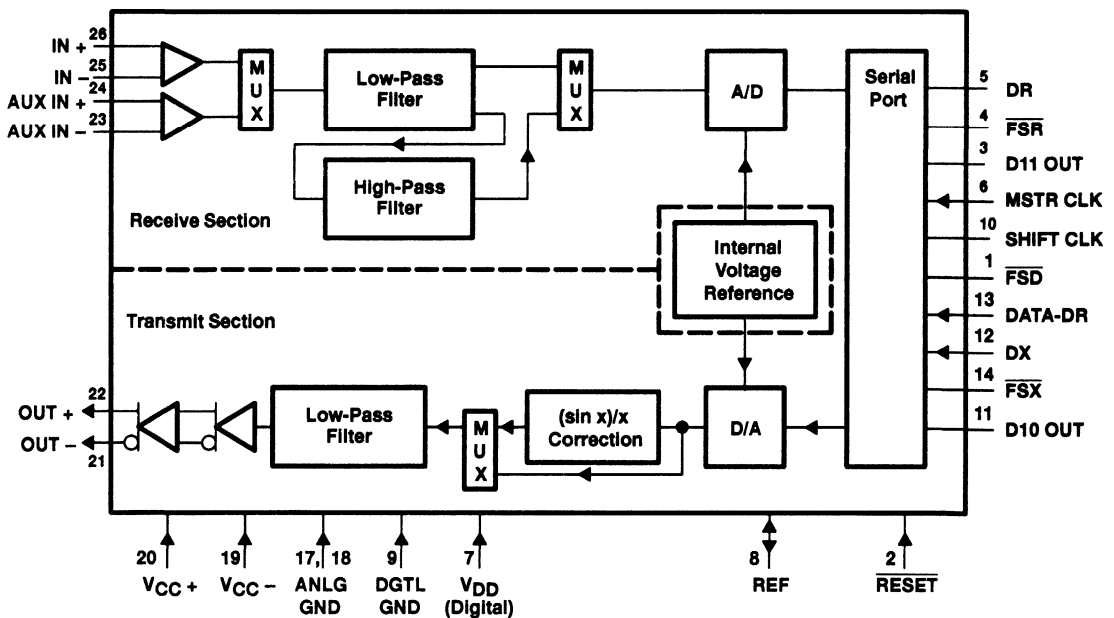
DATA FORMAT	SYNCHRONOUS (CONTROL REGISTER BIT D5 = 1)	ASYNCHRONOUS (CONTROL REGISTER BIT D5 = 0)	FORCING CONDITION	DIRECT INTERFACE
16-bit format	Dual-word (telephone interface) mode	Dual-word (telephone interface) mode	DATA-DR/CONTROL = 0 to 5 V FSD/WORD-BYTE = 0 to 5 V	TMS32020, TMS320C25, TMS320C30
16-bit format	Word mode	Word mode	DATA-DR/CONTROL = V_{CC-} (–5 V nom) FSD/WORD-BYTE = V_{CC+} (5 V nom)	TMS32020, TMS320C25, TMS320C30, indirect interface to TMS320C10 (see Figure 7)
8-bit format (2 bytes required)	Byte mode	Byte mode	DATA-DR/CONTROL = V_{CC-} (–5 V nom) FSD/WORD-BYTE = V_{CC-} (–5 V nom)	TMS320C17

1.2 Functional Block Diagrams

WORD OR BYTE MODE



DUAL-WORD (TELEPHONE INTERFACE) MODE



FRAME SYNCHRONIZATION FUNCTIONS

TLC32047 Function	Frame Sync Output
Receiving serial data on DX from processor to internal DAC	$\overline{\text{FSX}}$ low
Transmitting serial data on DR from internal ADC to processor, primary communications	$\overline{\text{FSR}}$ low
Transmitting serial data on DR from DATA-DR to processor, secondary communications in dual-word (telephone interface) mode only	$\overline{\text{FSD}}$ low

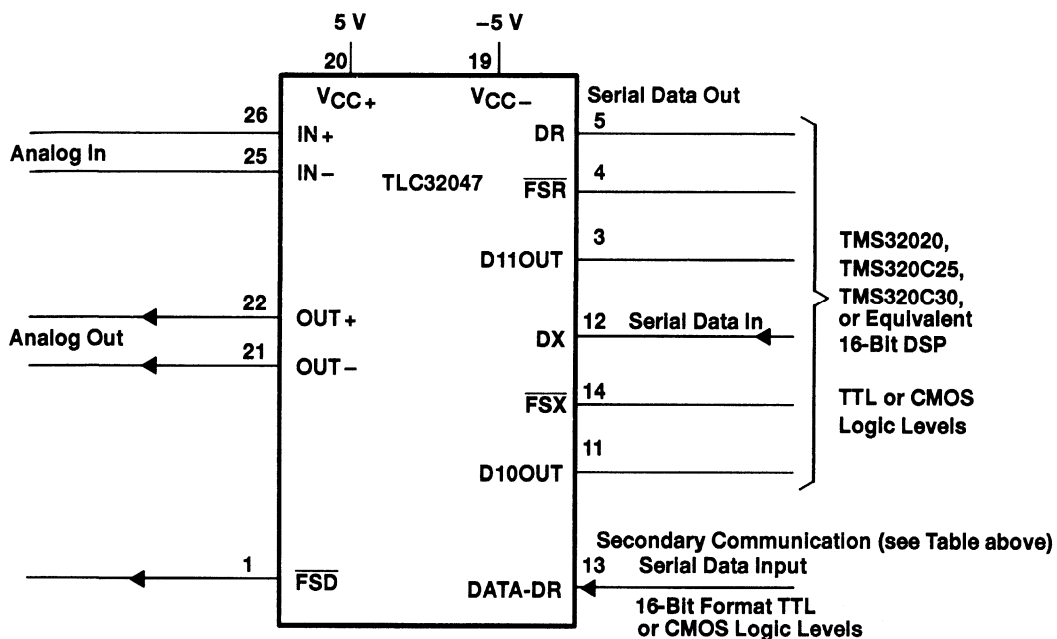


Figure 1-1. Dual-Word (Telephone Interface) Mode

When the DATA-DR/CONTROL input is tied to a logic signal source varying between 0 and 5 V, the TLC32047 is in the dual-word (telephone interface) mode. This logic signal is routed to the DR line for input to the DSP only when terminal 1, data frame synchronization ($\overline{\text{FSD}}$), outputs a low level. The $\overline{\text{FSD}}$ pulse duration is 16 shift clock pulses. Also, in this mode, the control register data bits D10 and D11 appear on D10OUT and D11OUT, respectively, as outputs.

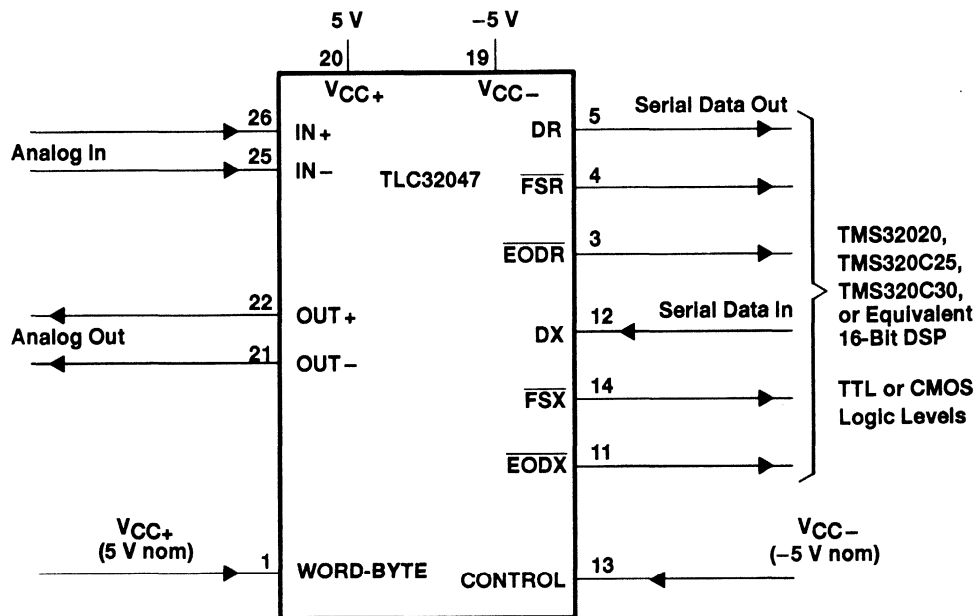


Figure 1-2. Word Mode

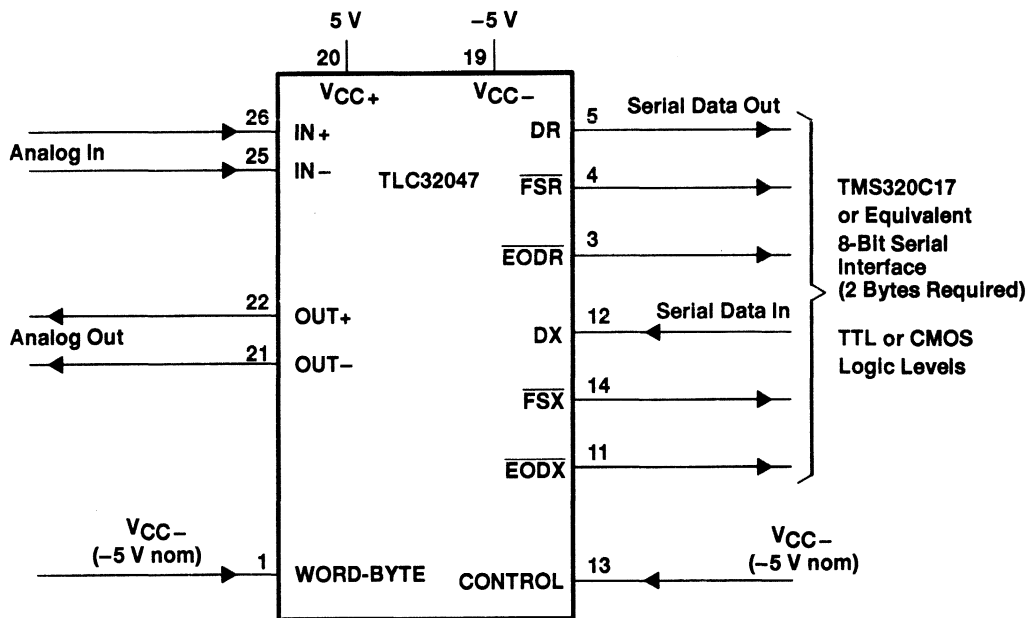
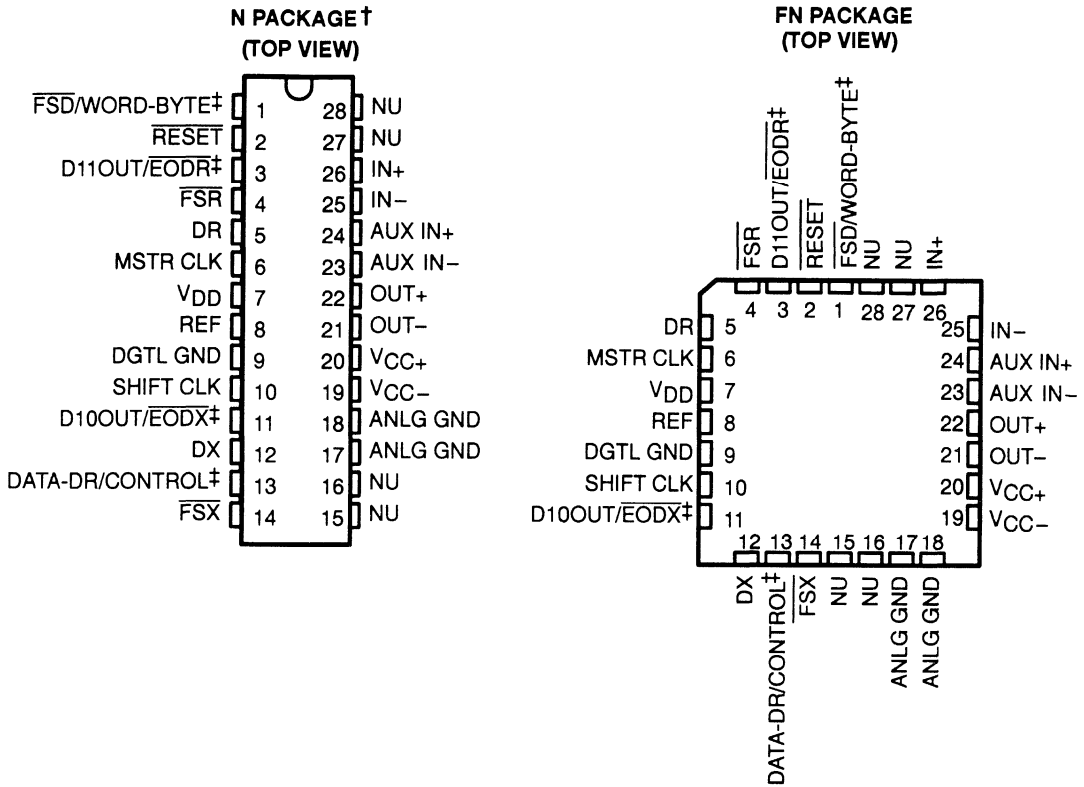


Figure 1-3. Byte Mode

The word or byte mode is selected by first connecting the DATA-DR/CONTROL input to V_{CC-} . \overline{FSD} /WORD-BYTE becomes an input and can then be used to select either word or byte transmission formats. The end-of-data transmit (\overline{EODX}) and the end-of-data receive (\overline{EODR}) signals on terminals 11 and 3, respectively, are used to signal the end of word or byte communication (see the Terminal Functions section).

1.3 Terminal Assignments



NU - Nonusable; no external connection should be made to these pins.

† 600-mil wide

‡ The portion of the terminal name to the left of the slash is used for the dual-word (telephone interface) mode. The portion of the terminal name to the right of the slash is used for word-byte mode.

1.4 Ordering Information

AVAILABLE OPTIONS

T _A	PACKAGED DEVICES	
	PLASTIC CHIP CARRIER (FN)	PLASTIC DIP (N)
0°C to 70°C	TLC32047CFN	TLC32047CN
-40°C to 85°C	TLC32047IFN	TLC32047IN

1.5 Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
ANLG GND	17,18		Analog ground return for all internal analog circuits. ANLG GND is internally connected to DGTL GND.
AUX IN+	24	I	Noninverting auxiliary analog input stage. AUX IN+ can be switched into the band-pass filter and ADC path via software control. If the appropriate bit in the control register is a 1, the auxiliary inputs replace the IN+ and IN- inputs. If the bit is a 0, the IN+ and IN- inputs are used (see the DX Serial Data Word Format).
AUX IN-	23	I	Inverting auxiliary analog input (see the above AUX IN+ description).
DATA-DR	13	I	The dual-word (telephone interface) mode, selected by applying an input logic level between 0 and 5 V to DATA-DR, allows DATA-DR to function as a data input. The data is then framed by the $\overline{\text{FSD}}$ signal and transmitted as an output to DR during secondary communication. The functions $\overline{\text{FSD}}$, D11OUT, and D10OUT are valid with this mode selection (see Table 2-1).
CONTROL			When CONTROL is tied to V_{CC-} , the device is in the word or byte mode. The functions WORD-BYTE, $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are valid in this mode. $\overline{\text{FSD}}$ /WORD-BYTE is then used to select either the word or byte mode (see Function Table).
DR	5	O	DR is used to transmit the ADC output bits from the AIC to the TMS320 serial port. This transmission of bits from the AIC to the TMS320 serial port is synchronized with the SHIFT CLK signal.
DX	12	I	DX is used to receive the DAC input bits and timing and control information from the TMS320. This serial transmission from the TMS320 serial port is synchronized with the SHIFT CLK signal.
D10OUT	11	O	in the dual-word (telephone interface) mode, bit D10 of the control register is output to D10OUT. When the device is reset, bit D10 is initialized to 0 (see DX Serial Data Word Format). The output update is immediate upon changing bit D10.
EODX			End of data transmit. During the word-mode timing, a low-going pulse occurs on EODX immediately after the 16 bits of DAC and control or register information have been transmitted from the TMS320 serial port to the AIC. EODX can be used to interrupt a microprocessor upon completion of serial communications. Also, EODX can be used to strobe and enable external serial-to-parallel shift registers, latches, or external FIFO RAM and to facilitate parallel data bus communications between the DSP and the serial-to-parallel shift registers. During the byte-mode timing, EODX goes low after the first byte has been transmitted from the TMS320 serial port to the AIC and is kept low until the second byte has been transmitted. The TMS320C17 can use this low-going signal to differentiate first and second bytes.

1.5 Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
D11OUT	3	O	In the dual-word (telephone interface) mode, bit D11 of the control register is output to D11OUT. When the device is reset, bit D11 is initialized to 0 (see DX Serial Data Word Format). The output update is immediate upon changing bit D11.
EODR			End of data receive. During the word-mode timing, a low-going pulse occurs on EODR immediately after the 16 bits of A/D information have been transmitted from the AIC to the TMS320 serial port. EODR can be used to interrupt a microprocessor upon completion of serial communications. Also, EODR can be used to strobe and enable external serial-to-parallel shift registers, latches, or external FIFO RAM, and to facilitate parallel data bus communications between the DSP and the serial-to-parallel shift registers. During the byte-mode timing, EODR goes low after the first byte has been transmitted from the AIC to the TMS320 serial port and is kept low until the second byte has been transmitted. The TMS320C17 can use this low-going signal to differentiate between first and second bytes.
DGTL GND	9		Digital ground for all internal logic circuits. Not internally connected to ANLG GND.
$\overline{\text{FSD}}$	1	O	Frame sync data. The $\overline{\text{FSD}}$ output remains high during primary communication. In the dual-word (telephone interface) mode, the $\overline{\text{FSD}}$ output is identical to the $\overline{\text{FSX}}$ output during secondary communication.
WORD-BYTE		I	WORD-BYTE allows differentiation between the word and byte data format (see DATA-DR/CONTROL and Table 2-1 for details).
$\overline{\text{FSR}}$	4	O	Frame sync receive. $\overline{\text{FSR}}$ is held low during bit transmission. When $\overline{\text{FSR}}$ goes low, the TMS320 serial port begins receiving bits from the AIC via DR of the AIC. The most significant DR bit is present on DR before FSR goes low (see Serial Port Sections and Internal Timing Configuration Diagrams).
$\overline{\text{FSX}}$	14	O	Frame sync transmit. When $\overline{\text{FSX}}$ goes low, the TMS320 serial port begins transmitting bits to the AIC via DX of the AIC. $\overline{\text{FSX}}$ is held low during bit transmission (see Serial Port Sections and Internal Timing Configuration Diagrams).
IN+	26	I	Noninverting input to analog input amplifier stage
IN-	25	I	Inverting input to analog input amplifier stage
MSTR CLK	6	I	Master clock. MSTR CLK is used to derive all the key logic signals of the AIC, such as the shift clock, the switched-capacitor filter clocks, and the A/D and D/A timing signals. The internal timing configuration diagram shows how these key signals are derived. The frequencies of these signals are synchronous submultiples of the master clock frequency to eliminate unwanted aliasing when the sampled analog signals are transferred between the switched-capacitor filters and the ADC and DAC converters (see the Internal Timing Configuration).
OUT+	22	O	Noninverting output of analog output power amplifier. OUT+ drives transformer hybrids or high-impedance loads directly in a differential or a single-ended configuration.
OUT-	21	O	Inverting output of analog output power amplifier. OUT- is functionally identical with and complementary to OUT+.
REF	8	I/O	Internal voltage reference is brought out on REF. An external voltage reference can be applied to REF to override the internal voltage reference.

1.5 Terminal Functions (continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION
$\overline{\text{RESET}}$	2	I	<p>Reset. A reset function is provided to initialize TA, TA', TB, RA, RA', RB (see Figure 2-1), and the control registers. This reset function initiates serial communications between the AIC and DSP. The reset function initializes all AIC registers, including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC registers are initialized to provide a 16-kHz data conversion rate for a 10.368-MHz master clock input signal. The conversion rate adjust registers, TA' and RA', are reset to 1. The CONTROL register bits are reset as follows (see AIC DX Data Word Format section):</p> <p style="padding-left: 2em;">D11 = 0, D10 = 0, D9 = 1, D7 = 1, D6 = 1, D5 = 1, D4 = 0, D3 = 0, D2 = 1</p> <p>The shift clock (SCLK) is held high during $\overline{\text{RESET}}$. This initialization allows normal serial-port communication to occur between the AIC and the DSP.</p>
SHIFT CLK	10	O	Shift clock. SHIFT CLK is obtained by dividing the master clock signal frequency by four. SHIFT CLK is used to clock the serial data transfers of the AIC.
VDD	7		Digital supply voltage, 5 V \pm 5%
VCC+	20		Positive analog supply voltage, 5 V \pm 5%
VCC-	19		Negative analog supply voltage, -5 V \pm 5%

2 Detailed Description

Table 2-1. Mode-Selection Function Table

DATA-DR/ CONTROL	$\overline{\text{FSD}}$ / WORD-BYTE	CONTROL REGISTER BIT (D5)	OPERATING MODE	SERIAL CONFIGURATION	DESCRIPTION
Data in (0 to 5 V)	$\overline{\text{FSD}}$ out (0 to 5 V)	1	Dual-Word (Telephone Interface)	Synchronous, One 16-Bit Word	Terminal functions DATA-DR [†] , $\overline{\text{FSD}}$ [†] , D11OUT, and D10OUT are applicable in this configuration. $\overline{\text{FSD}}$ is asserted during secondary communication, but the $\overline{\text{FSR}}$ is not asserted. However, $\overline{\text{FSD}}$ remains high during primary communication.
Data in (0 to 5 V)	$\overline{\text{FSD}}$ out (0 to 5 V)	0	Dual-Word (Telephone Interface)	Asynchronous, One 16-bit Word	Terminal functions DATA-DR [†] , $\overline{\text{FSD}}$ [†] , D11OUT, and D10OUT are applicable in this configuration. $\overline{\text{FSD}}$ is asserted during secondary communication, but the $\overline{\text{FSR}}$ is not asserted. However, $\overline{\text{FSD}}$ remains high during primary communication. If secondary communications occur while the A/D conversion is being transmitted from DR, $\overline{\text{FSD}}$ cannot go low, and data from DATA-DR cannot go onto DR.
V_{CC-}	V_{CC+}	1	WORD	Synchronous, One 16-Bit Word	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.
		0		Asynchronous, One 16-bit Word	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.
	V_{CC-}	1	BYTE	Synchronous, Two 8-Bit Bytes	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.
		0		Asynchronous, Two 8-Bit Bytes	Terminal functions CONTROL [†] , WORD-BYTE [†] , $\overline{\text{EODR}}$, and $\overline{\text{EODX}}$ are applicable in this configuration.

[†] DATA-DR/CONTROL has an internal pulldown resistor to -5 V, and $\overline{\text{FSD}}$ /WORD-BYTE has an internal pullup resistor to 5 V.

2.1 Internal Timing Configuration (see Figure 2–1)

All the internal timing of the AIC is derived from the high-frequency clock signal that drives the master clock input. The shift clock signal, which strobes the serial port data between the AIC and DSP, is derived by dividing the master clock input signal frequency by four.

The TX(A) counter and the TX(B) counter, which are driven by the master clock signal, determine the D/A conversion timing. Similarly, the RX(A) counter and the RX(B) counter determine the A/D conversion timing. In order for the low-pass switched-capacitor filter in the D/A path (see Functional Block Diagram) to meet its transfer function specifications, the frequency of its clock input must be 432 kHz. If the clock frequency is not 432 kHz, the filter transfer function frequencies are frequency-scaled by the ratios of the clock frequency to 432 kHz:

$$\text{Absolute Frequency (kHz)} = \frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{432} \quad (1)$$

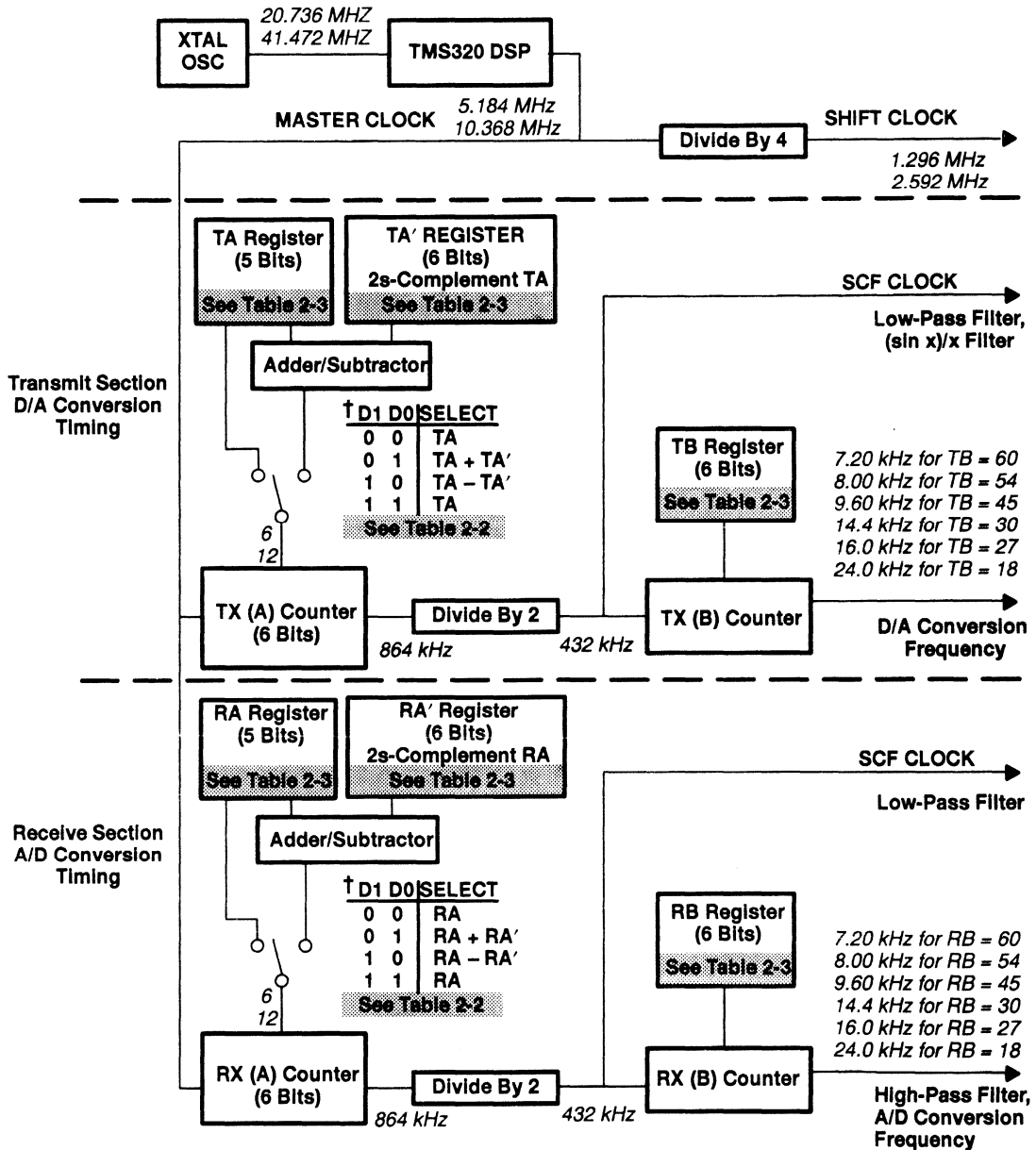
To obtain the specified filter response, the combination of master clock frequency and the TX(A) counter and the RX(A) counter values must yield a 432-kHz switched-capacitor clock signal. This 432-kHz clock signal can then be divided by the TX(B) counter to establish the D/A conversion timing.

The transfer function of the band-pass switched-capacitor filter in the A/D path (see Functional Block Diagram) is a composite of its high-pass and low-pass transfer functions. When the shift clock frequency (SCF) is 432 kHz, the high-frequency roll-off of the low-pass section meets the band-pass filter transfer function specification. Otherwise, the high-frequency roll-off is frequency-scaled by the ratio of the high-pass section's SCF clock to 432 kHz (see Figure 5–5). The low-frequency roll-off of the high-pass section meets the band-pass filter transfer function specification when the A/D conversion rate is 24 kHz. If not, the low-frequency roll-off of the high-pass section is frequency-scaled by the ratio of the A/D conversion rate to 24 kHz.

The TX(A) counter and the TX(B) counter are reloaded each D/A conversion period, while the RX(A) counter and the RX(B) counter are reloaded every A/D conversion period. The TX(B) counter and the RX(B) counter are loaded with the values in the TB and RB registers, respectively. Via software control, the TX(A) counter can be loaded with the TA register, the TA register less the TA' register, or the TA register plus the TA' register. By selecting the TA register less the TA' register option, the upcoming conversion timing occurs earlier by an amount of time that equals TA' times the signal period of the master clock. If the TA register plus the TA' register option is executed, the upcoming conversion timing occurs later by an amount of time that equals TA' times the signal period of the master clock. Thus, the D/A conversion timing can be advanced or retarded. An identical ability to alter the A/D conversion timing is provided. However, the RX(A) counter can be programmed via software control with the RA register, the RA register less the RA' register, or the RA register plus the RA' register.

The ability to advance or retard conversion timing is particularly useful for modem applications. This feature allows controlled changes in the A/D and D/A conversion timing and can be used to enhance signal-to-noise performance, to perform frequency-tracking functions, and to generate nonstandard modem frequencies.

If the transmit and receive sections are configured to be synchronous, then the low-pass and band-pass switched-capacitor filter clocks are derived from the TX(A) counter. Also, both the D/A and A/D conversion timings are derived from the TX(A) counter and the TX(B) counter. When the transmit and receive sections are configured to be asynchronous, the RX(A) counter, RX(B) counter, RA register, RA' register, and RB registers are not used.



† These control bits are described in the DX Serial Data Word Format section.

NOTES: D. Tables 2-2 and 2-3 (pages 2-9 and 2-10) are primary and secondary communication protocols, respectively.

E. In synchronous operation, RA, RA', RB, RX(A), and RX(B) are not used. TA, TA', TB, TX(A), and TX(B) are used instead.

F. Items in italics refer only to frequencies and register contents, which are variable. A crystal oscillator driving 20.736 MHz into the TMS320-series DSP provides a master clock frequency of 5.184 MHz. The TLC32047 produces a shift clock frequency of 1.296 MHz. If the TX(A) register contents equal 6, the SCF clock frequency is then 432 kHz, and the D/A conversion frequency is 432 kHz + T(B).

Figure 2-1. Asynchronous Internal Timing Configuration

2.2 Analog Input

Two pairs of analog inputs are provided. Normally, the IN+ and IN– input pair is used; however, the auxiliary input pair, AUX IN+ and AUX IN–, can be used if a second input is required. Since sufficient common-mode range and rejection are provided, each input set can be operated in differential or single-ended modes. The gain for the IN+, IN–, AUX IN+, and AUX IN– inputs can be programmed to 1, 2, or 4 (see Table 4–1). Either input circuit can be selected via software control. Multiplexing is controlled with the D4 bit (enable/disable AUX IN+ and AUX IN–) of the secondary DX word (see Table 2–3). The multiplexing requires a 2-ms wait at SCF = 432 kHz (see Figure 5–3) for a valid output signal. A wide dynamic range is ensured by the differential internal analog architecture and the separate analog and digital voltage supplies and grounds.

2.3 A/D Band-Pass Filter, A/D Band-Pass Filter Clocking, and A/D Conversion Timing

The receive-channel A/D high-pass filter can be selected or bypassed via software control (see Functional Block Diagram). The frequency response of this filter is on page 3-5. This response results when the switched-capacitor filter clock frequency is 432 kHz and the A/D sample rate is 24 kHz. Several possible options can be used to attain a 432-kHz switched-capacitor filter clock. When the filter clock frequency is not 432 kHz, the low-pass filter transfer function is frequency-scaled by the ratio of the actual clock frequency to 432 kHz (see Typical Characteristics section). The ripple bandwidth and 3-dB low-frequency roll-off points of the high-pass section are 450 Hz and 300 Hz, respectively. However, the high-pass section low-frequency roll-off is frequency-scaled by the ratio of the A/D sample rate to 24 kHz.

Figure 2–1 and the DX Serial Data Word Format sections of this data manual indicate the many options for attaining a 432-kHz band-pass switched-capacitor filter clock. These sections indicate that the RX(A) counter can be programmed to give a 432-kHz band-pass switched-capacitor filter clock for several master clock input frequencies.

The A/D conversion rate is attained by frequency-dividing the band-pass switched-capacitor filter clock with the RX(B) counter. Unwanted aliasing is prevented because the A/D conversion rate is an integer submultiple of the band-pass switched-capacitor filter sampling rate, and the two rates are synchronously locked.

2.4 A/D Converter

Fundamental performance specifications for the receive channel ADC circuitry are on pages 3-2 and 3-3 of this data manual. The ADC circuitry, using switched-capacitor techniques, provides an inherent sample-and-hold function.

2.5 Analog Output

The analog output circuitry is an analog output power amplifier. Both noninverting and inverting amplifier outputs are brought out of the IC. This amplifier can drive transformer hybrids or low-impedance loads directly in either a differential or single-ended configuration.

2.6 D/A Low-Pass Filter, D/A Low-Pass Filter Clocking, and D/A Conversion Timing

The frequency response of these filters is on page 3-5. This response results when the low-pass switched-capacitor filter clock frequency is 432 kHz (see Equation 1). Like the A/D filter, the transfer function of this filter is frequency-scaled when the clock frequency is not 432 kHz (see Typical Characteristics section). A continuous-time filter is provided on the output of the low-pass filter to eliminate the periodic sample data signal information, which occurs at multiples of the 432-kHz switched-capacitor clock feedthrough.

The D/A conversion rate is attained by frequency-dividing the 432-kHz switched-capacitor filter clock with the T(B) counter. Unwanted aliasing is prevented because the D/A conversion rate is an integer submultiple of the switched-capacitor low-pass filter sampling rate, and the two rates are synchronously locked.

2.7 D/A Converter

Fundamental performance specifications for the transmit channel DAC circuitry are on pages 3-3 and 3-4. The DAC has a sample-and-hold function that is realized with a switched-capacitor ladder.

2.8 Serial Port

The serial port has four possible configurations summarized in the function table on page 1-2. These configurations are briefly described below.

- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS320C17. The communications protocol is two 8-bit bytes.
- The transmit and receive sections are operated asynchronously, and the serial port interfaces directly with the TMS32020, TMS320C25, and TMS320C30. The communications protocol is one 16-bit word.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS320C17. The communications protocol is two 8-bit bytes.
- The transmit and receive sections are operated synchronously, and the serial port interfaces directly with the TMS32020, TMS320C25, TMS320C30, or two SN74299 serial-to-parallel shift registers, which can interface in parallel to the TMS32010, TMS320C15, to any other digital signal processor, or to external FIFO circuitry. The communications protocol is one 16-bit word.

2.9 Synchronous Operation

When the transmit and receive sections are operated synchronously, the low-pass filter clock drives both low-pass and band-pass filters (see Functional Block Diagram). The A/D conversion timing is derived from and equal to the D/A conversion timing. When data bit D5 in the control register is a logic 1, transmit and receive sections are synchronous. The band-pass switched-capacitor filter and the A/D converter timing are derived from the TX(A) counter, the TX(B) counter, and the TA and TA' registers. In synchronous operation, both the A/D and the D/A channels operate from the same frequencies. The \overline{FSX} and the \overline{FSR} timing is identical during primary communication, but \overline{FSR} is not asserted during secondary communication because there is no new A/D conversion result.

2.9.1 One 16-Bit Word [Dual-Word (Telephone Interface) or Word Mode]

The serial port interfaces directly with the serial ports of the TMS32020, TMS320C25, and the TMS320C30, and communicates in one 16-bit word. The operation sequence is as follows:

1. \overline{FSX} and \overline{FSR} are brought low by the TLC32047 AIC.
2. One 16-bit word is transmitted and one 16-bit word is received.
3. \overline{FSX} and \overline{FSR} are brought high.
4. \overline{EODX} and \overline{EODR} emit low-going pulses one shift clock wide. \overline{EODX} and \overline{EODR} are valid in the word or byte mode only.

If the device is in the dual-word (telephone interface) mode, \overline{FSD} goes low during the secondary communication period and enables the data word received at the DATA-DR/CONTROL input to be routed to the DR line. The secondary communication period occurs four shift clocks after completion of primary communications.

2.9.2 Two 8-Bit Bytes (Byte Mode)

The serial port interfaces directly with the serial port of the TMS320C17 and communicates in two 8-bit bytes. The operation sequence is as follows:

1. \overline{FSX} and \overline{FSR} are brought low.
2. One 8-bit word is transmitted and one 8-bit word is received.
3. \overline{EODX} and \overline{EODR} are brought low.
4. \overline{FSX} and \overline{FSR} emit positive frame-sync pulses that are four shift clock cycles wide.
5. One 8-bit byte is transmitted and one 8-bit byte is received.
6. \overline{FSX} and \overline{FSR} are brought high.
7. \overline{EODX} and \overline{EODR} are brought high.

2.9.3 Synchronous Operating Frequencies

The synchronous operating frequencies are determined by the following equations.

Switched capacitor filter (SCF) frequencies (see Figure 2-1):

$$\text{Low-pass SCF clock frequency (D/A and A/D channels)} = \frac{\text{master clock frequency}}{T(A) \times 2}$$

$$\text{High-pass SCF clock frequency (A/D channel)} = \text{A/D conversion frequency}$$

$$\begin{aligned} \text{Conversion frequency (A/D and D/A channels)} &= \frac{\text{Low pass SCF clock frequency}}{T(B)} \\ &= \frac{\text{master clock frequency}}{T(A) \times 2 \times T(B)} \end{aligned}$$

NOTE: T(A), T(B), R(A), and R(B) are the contents of the TA, TB, RA, and RB registers, respectively.

2.10 Asynchronous Operation

When the transmit and the receive sections are operated asynchronously, the low-pass and band-pass filter clocks are independently generated from the master clock. The D/A and the A/D conversion timing is also determined independently.

D/A timing is set by the counters and registers described in synchronous operation, but the RA and RB registers are substituted for the TA and TB registers to determine the A/D channel sample rate and the A/D path switched-capacitor filter frequencies. Asynchronous operation is selected by control register bit D5 being zero.

2.10.1 One 16-Bit Word (Word Mode)

The serial port interfaces directly with the serial ports of the TMS32020, TMS320C25, and TMS320C30 and communicates with 16-bit word formats. The operation sequence is as follows:

1. \overline{FSX} or \overline{FSR} are brought low by the TLC32047 AIC.
2. One 16-bit word is transmitted or one 16-bit word is received.
3. \overline{FSX} or \overline{FSR} are brought high.
4. \overline{EODX} or \overline{EODR} emit low-going pulses one shift clock wide. \overline{EODX} and \overline{EODR} are valid in either the word or byte mode only.

2.10.2 Two 8-Bit Bytes (Byte Mode)

The serial port interfaces directly with the serial port of the TMS320C17 and communicates in two 8-bit bytes. The operating sequence is as follows:

1. \overline{FSX} or \overline{FSR} are brought low by the TLC32047 AIC.
2. One byte is transmitted or received.

3. \overline{EODX} or \overline{EODR} are brought low.
4. \overline{FSX} or \overline{FSR} are brought high for four shift clock periods and then brought low.
5. The second byte is transmitted or received.
6. \overline{FSX} or \overline{FSR} are brought high.
7. \overline{EODX} or \overline{EODR} are brought high.

2.10.3 Asynchronous Operating Frequencies

The asynchronous operating frequencies are determined by the following equations.

Switched-capacitor filter frequencies (see Figure 2–1):

$$\text{Low pass D/A SCF clock frequency} = \frac{\text{master clock frequency}}{T(A) \times 2}$$

$$\text{Low pass A/D SCF clock frequency} = \frac{\text{master clock frequency}}{R(A) \times 2}$$

$$\text{High pass SCF clock frequency (A/D channel)} = \text{A/D conversion frequency} \quad (2)$$

Conversion frequency:

$$\text{D/A conversion frequency} = \frac{\text{Low pass D/A SCF clock frequency}}{T(B)}$$

$$\text{A/D conversion frequency} = \frac{\text{Low pass A/D SCF clock frequency (for low pass receive filter)}}{R(B)} \quad (3)$$

NOTE: T(A), T(B), R(A), and R(B) are the contents of the TA, TB, RA, and RB registers, respectively.

2.11 Operation of TLC32047 With Internal Voltage Reference

The internal reference of the TLC32047 eliminates the need for an external voltage reference and provides overall circuit cost reduction. The internal reference eases the design task and provides complete control of the IC performance. The internal reference is brought out to REF. To keep the amount of noise on the reference signal to a minimum, an external capacitor can be connected between REF and ANLG GND.

2.12 Operation of TLC32047 With External Voltage Reference

REF can be driven from an external reference circuit. This external circuit must be capable of supplying 250 μA and must be protected adequately from noise and crosstalk from the analog input.

2.13 Reset

A reset function is provided to initiate serial communications between the AIC and DSP and to allow fast, cost-effective testing during manufacturing. The reset function initializes all AIC registers, including the control register. After a negative-going pulse on $\overline{\text{RESET}}$, the AIC is initialized. This initialization allows normal serial port communications activity to occur between AIC and DSP (see AIC DX Data Word Format section). After a reset, TA=TB=RA=RB=18 (or 12 hexadecimal), TA'=RA'=01 (hexadecimal), the A/D high-pass filter is inserted, the loop-back function is deleted, AUX IN+ and AUX IN– are disabled, the transmit and receive sections are in synchronous operation, programmable gain is set to 1, the on-board (sin x)/x correction filter is not selected, D10 OUT is set to 0, and D11 OUT is set to 0.

2.14 Loopback

This feature allows the circuit to be tested remotely. In loopback, OUT+ and OUT– are internally connected to IN+ and IN–. The DAC bits (D15 to D2), which are transmitted to DX, can be compared with the ADC bits (D15 to D2) received from DR. The bits on DR equal the bits on DX. However, there is some difference in these bits due to the ADC and DAC output offsets.

The loopback feature is implemented with digital signal processor control by transmitting a logic 1 for data bit D3 in the DX secondary communication to the control register (see Table 2–3).

2.15 Communications Word Sequence

In the dual-word (telephone interface) mode, there are two data words that are presented to the DSP or μP from DR. The first data word is the ADC conversion result occurring during the FSR time, and the second is the serial data applied to DATA-DR during the FSD time. FSR is not asserted during secondary communications and FSD is not asserted during primary communications.

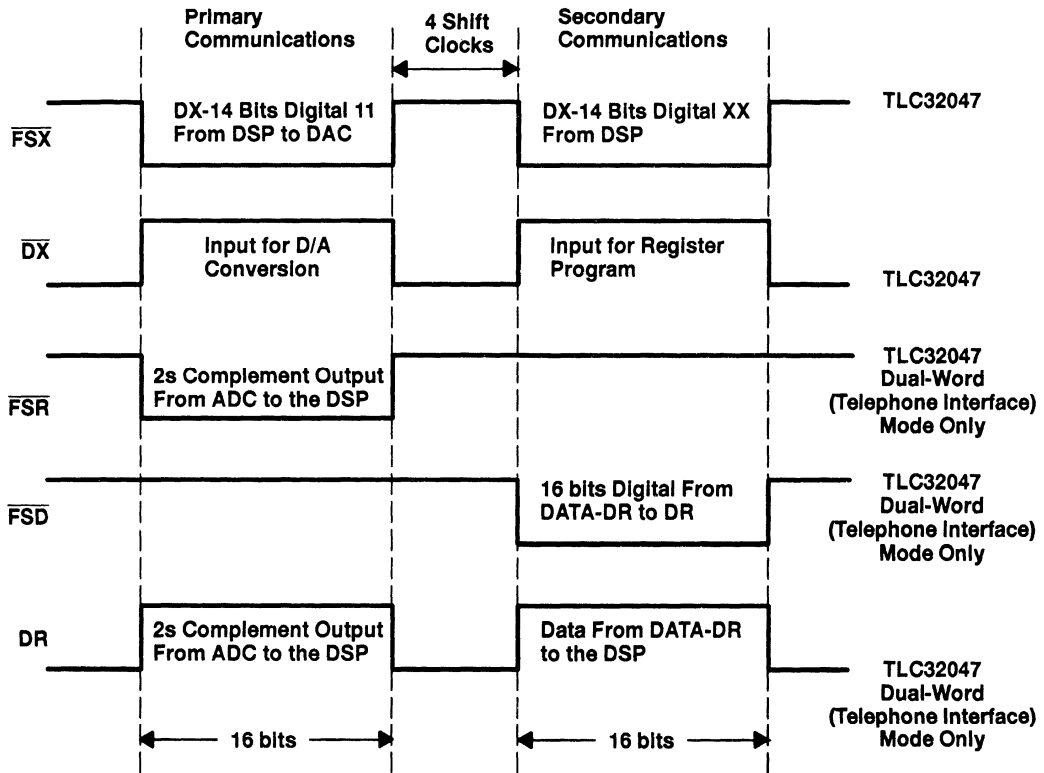
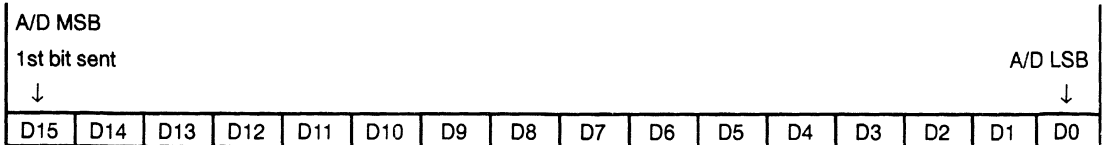


Figure 2-2. Primary and Secondary Communications Word Sequence

2.15.1 DR Word Bit Pattern



The data word is the 14-bit conversion result of the receive channel to the processor in 2s complement format. With 16-bit processors, the data is 16 bits long with the two LSBs at zero. Using 8-bit processors, the data word is transmitted in the same order as one 16-bit word, but as two bytes with the two LSBs of the second byte set to zero.

2.15.2 Primary DX Word Bit Pattern

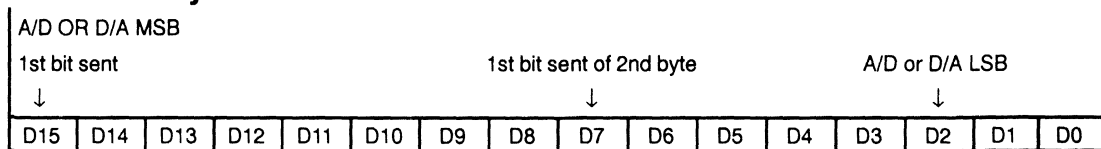


Table 2–2. Primary DX Serial Communication Protocol

FUNCTIONS	D1	D0
D15 (MSB)-D2 → DAC Register. TA → TX(A), RA → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1).	0	0
D15 (MSB)-D2 → DAC Register. TA+TA' → TX(A), RA+RA' → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1). The next D/A and A/D conversion period is changed by the addition of TA' and RA' master clock cycles, in which TA' and RA' can be positive, negative, or zero (refer to Table 2–4, AIC Responses to Improper Conditions).	0	1
D15 (MSB)-D2 → DAC Register. TA-TA' → TX(A), RA-RA' → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1). The next D/A and A/D conversion period is changed by the subtraction of TA' and RA' master clock cycles, in which TA' and RA' can be positive, negative, or zero (refer to Table 2–4, AIC Responses to Improper Conditions).	1	0
D15 (MSB)-D2 → DAC Register. TA → TX(A), RA → RX(A) (see Figure 2–1). TB → TX(B), RB → RX(B) (see Figure 2–1). After a delay of four shift cycles, a secondary transmission follows to program the AIC to operate in the desired configuration. In the telephone interface mode, data on DATA-DR is routed to DR (Serial Data Output) during secondary transmission.	1	1

NOTE: Setting the two least significant bits to 1 in the normal transmission of DAC information (primary communications) to the AIC initiates secondary communications upon completion of the primary communications. When the primary communication is complete, \overline{FSX} remains high for four shift clock cycles and then goes low and initiates the secondary communication. The timing specifications for the primary and secondary communications are identical. In this manner, the secondary communication, if initiated, is interleaved between successive primary communications. This interleaving prevents the secondary communication from interfering with the primary communications and DAC timing. This prevents the AIC from skipping a DAC output. \overline{FSR} is not asserted during secondary communications activity. However, in the dual-word (telephone interface) mode, \overline{FSD} is asserted during secondary communications but not during primary communications.

2.15.3 Secondary DX Word Bit Pattern

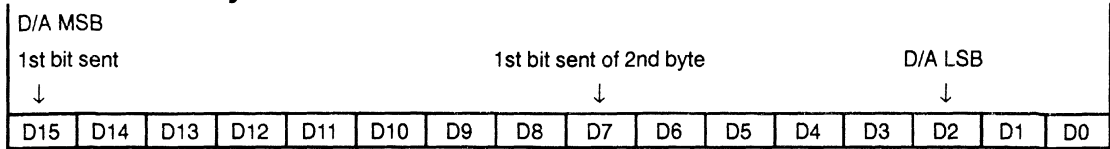


Table 2-3. Secondary DX Serial Communication Protocol

FUNCTIONS	D1	D0
D13 (MSB)-D9 → TA, 5 bits unsigned binary (see Figure 2-1). D6 (MSB)-D2 → RA, 5 bits unsigned binary (see Figure 2-1). D15, D14, D8, and D7 are unassigned.	0	0
D14 (sign bit)-D9 → TA', 6 bits 2s complement (see Figure 2-1). D7 (sign bit)-D2 → RA', 6 bits 2s complement (see Figure 2-1). D15 and D8 are unassigned.	0	1
D14 (MSB)-D9 → TB, 6 bits unsigned binary (see Figure 2-1). D7 (MSB)-D2 → RB, 6 bits unsigned binary (see Figure 2-1). D15 and D8 are unassigned.	1	0
D2 = 0/1 deletes/inserts the A/D high-pass filter. D3 = 0/1 deletes/inserts the loopback function. D4 = 0/1 disables/enables AUX IN+ and AUX IN-. D5 = 0/1 asynchronous/synchronous transmit and receive sections. D6 = 0/1 gain control bits (see Table 4-1). D7 = 0/1 gain control bits (see Table 4-1). D9 = 0/1 delete/insert on-board second-order (sin x)/x correction filter D10 = 0/1 output to D10OUT [dual-word (telephone interface) mode] D11 = 0/1 output to D11OUT [dual-word (telephone interface) mode] D8, D12-D15 are unassigned.	1	1

2.16 Reset Function

A reset function is provided to initiate serial communications between the AIC and DSP. The reset function initializes all AIC registers, including the control register. After power has been applied to the AIC, a negative-going pulse on RESET initializes the AIC registers to provide a 16-kHz A/D and D/A conversion rate for a 10.368-MHz master clock input signal. Also, the pass-bands of the A/D and D/A filters are 300 Hz to 7200 Hz and 0 Hz to 7200 Hz, respectively. Therefore, the filter bandwidths are 66% of those shown in the filter transfer function specification section. The AIC, excepting the control register, is initialized as follows (see AIC DX Data Word Format section):

REGISTER	TA	TA'	TB	RA	RA'	RB
INITIALIZED VALUE (HEX)	12	01	12	12	01	12

The control register bits are reset as follows (see Table 2-3):

$$D11 = 0, D10 = 0, D9 = 1, D7 = 1, D6 = 1, D5 = 1, D4 = 0, D3 = 0, D2 = 1$$

This initialization allows normal serial port communications to occur between the AIC and the DSP. If the transmit and receive sections are configured to operate synchronously and the user wishes to program different conversion rates, only the TA, TA', and TB register need to be programmed. Both transmit and receive timing are synchronously derived from these registers (see the Terminal Functions and DX Serial Data Word Format sections).

Figure 2-3 shows a circuit that provides a reset on power-up when power is applied in the sequence given in the Power-Up Sequence section. The circuit depends on the power supplies reaching their recommended values a minimum of 800 ns before the capacitor charges to 0.8 V above DGTL GND.

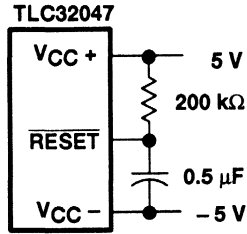


Figure 2–3. Reset on Power-Up Circuit

2.17 Power-Up Sequence

To ensure proper operation of the AIC and as a safeguard against latch-up, it is recommended that Schottky diodes with forward voltages less than or equal to 0.4 V be connected from V_{CC-} to ANLG GND and from V_{CC-} to DGTL GND. In the absence of such diodes, power is applied in the following sequence: ANLG GND and DGTL GND, V_{CC-} , then V_{CC+} and V_{DD} . Also, no input signal is applied until after power-up.

2.18 AIC Register Constraints

The following constraints are placed on the contents of the AIC registers:

1. TA register must be ≥ 4 in word mode (WORD/BYTE= High).
2. TA register must be ≥ 5 in byte mode (WORD/BYTE= Low).
3. TA' register can be either positive, negative, or zero.
4. RA register must be ≥ 4 in word mode (WORD/BYTE = High).
5. RA register must be ≥ 5 in byte mode (WORD/BYTE = Low).
6. RA' register can be either positive, negative, or zero.
7. (TA register \pm TA' register) must be > 1 .
8. (RA register \pm RA' register) must be > 1 .
9. TB register must be ≥ 15 .
10. RB register must be ≥ 15 .

2.19 AIC Responses to Improper Conditions

The AIC has provisions for responding to improper conditions. These improper conditions and the response of the AIC to these conditions are presented in Table 2–4. The general procedure for correcting any improper operation is to apply a reset and reprogram the registers to the proper value.

Table 2–4. AIC Responses to Improper Conditions

IMPROPER CONDITION	AIC RESPONSE
TA register + TA' register = 0 or 1 TA register – TA' register = 0 or 1	Reprogram TX(A) counter with TA register value
TA register + TA' register < 0	MODULO 64 arithmetic is used to ensure that a positive value is loaded into TX(A) counter, i.e., TA register + TA' register + 40 hex is loaded into TX(A) counter.
RA register + RA' register = 0 or 1 RA register – RA' register = 0 or 1	Reprogram RX(A) counter with RA register value
RA register + RA' register = 0 or 1	MODULO 64 arithmetic is used to ensure that a positive value is loaded into RX(A) counter, i.e., RA register + RA' register + 40 hex is loaded into RX(A) counter.
TA register = 0 or 1 RA register = 0 or 1	AIC is shut down. Reprogram TA or RA registers after a reset.
TA register < 4 in word mode TA register < 5 in byte mode RA register < 4 in word mode RA register < 5 in byte mode	The AIC serial port no longer operates. Reprogram TA or RA registers after a reset.
TB register < 15	ADC no longer operates
RB register < 15	DAC no longer operates
AIC and DSP cannot communicate	Hold last DAC output

2.20 Operation With Conversion Times Too Close Together

If the difference between two successive D/A conversion frame syncs is less than 1/25 kHz, the AIC operates improperly. In this situation, the second D/A conversion frame sync occurs too quickly, and there is not enough time for the ongoing conversion to be completed. This situation can occur if the A and B registers are improperly programmed or if the A + A' register result is too small. When incrementally adjusting the conversion period via the A + A' register options, the designer should not violate this requirement. See Figure 2–4.

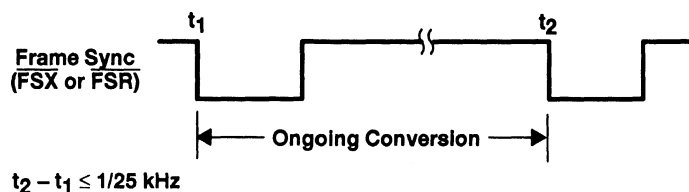


Figure 2–4. Conversion Times Too Close Together

2.21 More Than One Receive Frame Sync Occurring Between Two Transmit Frame Syncs – Asynchronous Operation

When incrementally adjusting the conversion period via the A + A' or A – A' register options, a specific protocol is followed. The command to use the incremental conversion period adjust option is sent to the AIC during an FSX frame sync. The ongoing conversion period is then adjusted; however, either receive conversion period A or conversion period B may be adjusted. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. If there is sufficient time between t_1 and t_2 , the receive conversion period adjustment is performed during receive conversion period A. Otherwise, the adjustment is performed during receive conversion period B. The adjustment command only adjusts one transmit conversion period and one receive conversion period. To adjust another pair of transmit and receive conversion periods, another command must be issued during a subsequent FSX frame (see Figure 2–5).

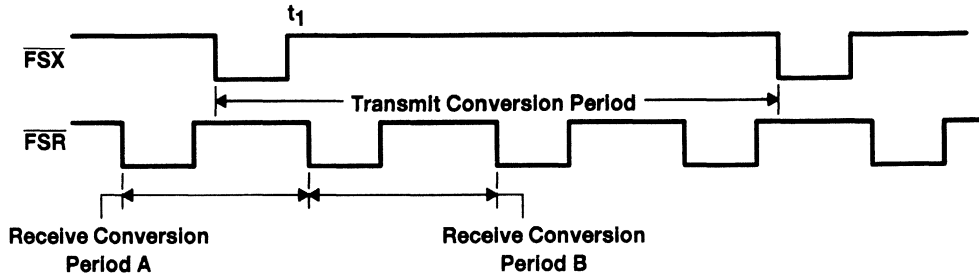


Figure 2-5. More Than One Receive Frame Sync Between Two Transmit Frame Syncs

2.22 More Than One Transmit Frame Sync Occurring Between Two Receive Frame Syncs – Asynchronous Operation

When incrementally adjusting the conversion period via the A + A' or A - A' register options, a specific protocol must be followed. For both transmit and receive conversion periods, the incremental conversion period adjustment is performed near the end of the conversion period. The command to use the incremental conversion period adjust options is sent to the AIC during an $\overline{\text{FSX}}$ frame sync. The ongoing transmit conversion period is then adjusted. However, three possibilities exist for the receive conversion period adjustment as shown in Figure 2-6. When the adjustment command is issued during transmit conversion period A, receive conversion period A is adjusted if there is sufficient time between t_1 and t_2 . If there is not sufficient time between t_1 and t_2 , receive conversion period B is adjusted. The third option is that the receive portion of an adjustment command can be ignored if the adjustment command is sent during a receive conversion period, which is adjusted due to a prior adjustment command. For example, if adjustment commands are issued during transmit conversion periods A, B, and C, the first two commands may cause receive conversion periods A and B to be adjusted, while the third receive adjustment command is ignored. The third adjustment command is ignored since it was issued during receive conversion period B, which already is adjusted via the transmit conversion period B adjustment command.

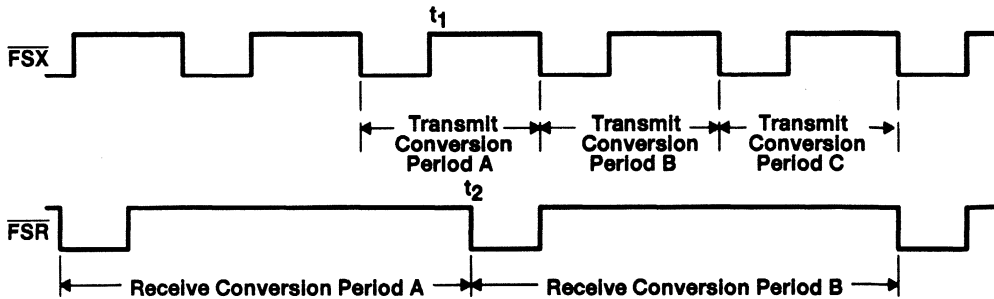


Figure 2-6. More Than One Transmit Frame Sync Between Two Receive Frame Syncs

2.23 More than One Set of Primary and Secondary DX Serial Communications Occurring Between Two Receive Frame Syncs (See DX Serial Data Word Format section) – Asynchronous Operation

The TA, TA', TB, and control register information that is transmitted in the secondary communication is accepted and applied during the ongoing transmit conversion period. If there is sufficient time between t_1 and t_2 , the TA, RA', and RB register information, sent during transmit conversion period A, is applied to receive conversion period A. Otherwise, this information is applied during receive conversion period B. If RA, RA', and RB register information has been received and is being applied during an ongoing conversion period, any subsequent RA, RA', or RB information received during this receive conversion period is disregarded. See Figure 2-7.

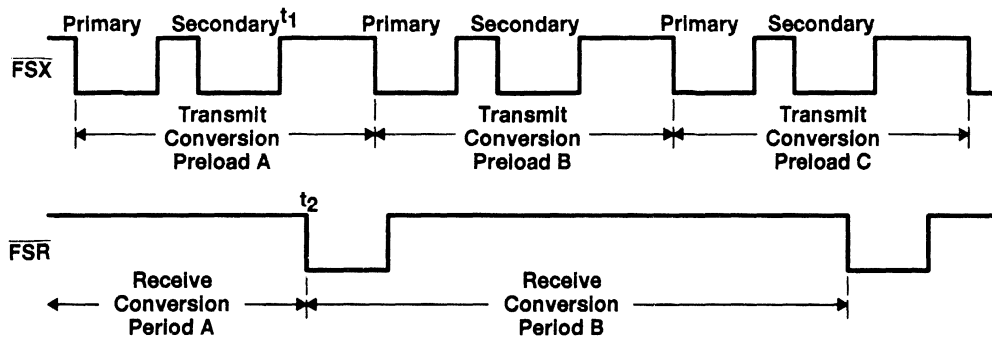


Figure 2–7. More Than One Set of Primary and Secondary DX Serial Communications Between Two Receive Frame Syncs

2.24 System Frequency Response Correction

The $(\sin x)/x$ correction for the DAC zero-order sample-and-hold output can be provided by an on-board second-order $(\sin x)/x$ correction filter (see Functional Block Diagram). This $(\sin x)/x$ correction filter can be inserted into or omitted from the signal path by digital-signal-processor control (data bit D9 in the DX secondary communications). When inserted, the $(\sin x)/x$ correction filter precedes the switched-capacitor low-pass filter. When the TB register (see Figure 2–1) equals 15, the correction results of Figures 5–8, 5–9, and 5–10 can be obtained.

The $(\sin x)/x$ correction can also be accomplished by disabling the on-board second-order correction filter and performing the $(\sin x)/x$ correction in digital signal processor software. The system frequency response can be corrected via DSP software to ± 0.1 dB accuracy to a band edge of 3000 Hz for all sampling rates. This correction is accomplished with a first-order digital correction filter, that requires seven TMS320 instruction cycles. With a 200-ns instruction cycle, seven instructions represent an overhead factor of 1.1% and 1.3% for sampling rates of 8 and 9.6 kHz, respectively (see the $(\sin x)/x$ Correction Section for more details).

2.25 $(\sin x)/x$ Correction

If the designer does not wish to use the on-board second-order $(\sin x)/x$ correction filter, correction can be accomplished in digital signal processor (DSP) software. $(\sin x)/x$ correction can be accomplished easily and efficiently in digital signal processor software. Excellent correction accuracy can be achieved to a band edge of 3000 Hz by using a first-order digital correction filter. The results shown below are typical of the numerical correction accuracy that can be achieved for sample rates of interest. The filter requires seven instruction cycles per sample on the TMS320 DSP. With a 200-ns instruction cycle, nine instructions per sample represents an overhead factor of 1.4% and 1.7% for sampling rates of 8000 Hz and 9600 Hz, respectively. This correction adds a slight amount of group delay at the upper edge of the 300-Hz to 3000-Hz band.

2.26 $(\sin x)/x$ Roll-Off for a Zero-Order Hold Function

The $(\sin x)/x$ roll-off error for the AIC DAC zero-order hold function at a band-edge frequency of 3000 Hz for the various sampling rates is shown in Table 2–5 (see Figure 5–10).

Table 2-5. $(\sin x)/x$ Roll-Off Error

f_s (Hz)	Error = $20 \log \frac{\sin \pi f/f_s}{\pi f/f_s}$ $f = 3000$ Hz (dB)
7200	-2.64
8000	-2.11
9600	-1.44
14400	-0.63
16000	-0.50
19200	-0.35
25000	-0.21

The actual AIC $(\sin x)/x$ roll-off is slightly less than the figures above because the AIC has less than 100% duty cycle hold interval.

2.27 Correction Filter

To externally compensate for the $(\sin x)/x$ roll-off of the AIC, a first-order correction filter can be implemented as shown in Figure 2-8.

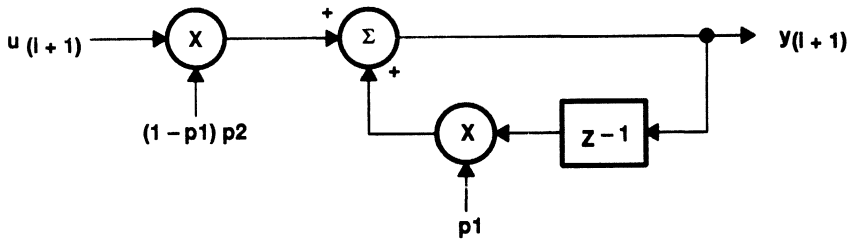


Figure 2-8. First-Order Correction Filter

The difference equation for this correction filter is:

$$y(i+1) = p2 \cdot (1-p1) \cdot u(i+1) + p1 \cdot y(i) \quad (4)$$

where the constant $p1$ determines the pole locations.

The resulting squared magnitude transfer function is:

$$|H(f)|^2 = \frac{(p2)^2 \cdot (1-p1)^2}{1 - 2 \cdot p1 \cdot \cos(2\pi f/f_s) + (p1)^2} \quad (5)$$

2.28 Correction Results

Table 2-6 shows the optimum p values and the corresponding correction results for 8000-Hz and 9600-Hz sampling rates (see Figures 5-8, 5-9, and 5-10).

Table 2–6. (sin x)/x Correction Table for $f_s = 8000$ Hz and $f_s = 9600$ Hz

f (Hz)	ROLL-OFF ERROR (dB)	
	$f_s = 8000$ Hz $p1 = -0.14813$ $p2 = 0.9888$	$f_s = 9600$ Hz $p1 = -0.1307$ $p2 = 0.9951$
300	-0.099	-0.043
600	-0.089	-0.043
900	-0.054	0
1200	-0.002	0
1500	0.041	0
1800	0.079	0.043
2100	0.100	0.043
2400	0.091	0.043
2700	-0.043	0
3000	-0.102	-0.043

2.29 TMS320 Software Requirements

The digital correction filter equation can be written in state variable form as follows:

$$Y_{(i+1)} = Y_{(i)} \times k1 + u_{(i+1)} \times k2$$

where

$$k1 = p1$$

$$k2 = (1 - p1)p2$$

$y(i)$ is the filter state

$u(i+1)$

The coefficients $k1$ and $k2$ must be represented as 16-bit integers. The SACH instruction (with the proper shift) yields the correct result. With the assumption that the TMS320 processor page pointer and memory configuration are properly initialized, the equation can be executed in seven instructions or seven cycles with the following program:

```
ZAC
LT K2
MPY U
LTA K1
MPY Y
APAC
SACH (dma), (shift)
```

3 Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (Unless Otherwise Noted)[†]

Supply voltage range, V_{CC+} (see Note 1)	-0.3 V to 15 V
Supply voltage range, V_{CC-} (see Note 1)	-0.3 V to 15 V
Supply voltage range, V_{DD}	-0.3 V to 15 V
Output voltage range, V_O	-0.3 V to 15 V
Input voltage range, V_I	-0.3 V to 15 V
Digital ground voltage range	-0.3 V to 15 V
Operating free-air temperature range: TLC32047C	0°C to 70°C
TLC32047I	-40°C to 85°C
Storage temperature range	-40°C to 125°C
Case temperature for 10 seconds: FN package	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: N package	...	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: Voltage values for maximum ratings are with respect to V_{CC-} .

3.2 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{CC+} (see Note 2)	4.75	5	5.25	V
Supply voltage, V_{CC-} (see Note 2)	-4.75	-5	-5.25	V
Digital supply voltage, V_{DD} (see Note 2)	4.75	5	5.25	V
Digital ground voltage with respect to ANLG GND, DGTL GND		0		V
Reference input voltage, $V_{ref(ext)}$ (see Note 2)	2		4	V
High-level input voltage, V_{IH}	2		V_{DD}	V
Low-level input voltage, V_{IL} (see Note 3)	0		0.8	V
Load resistance at OUT+ and/or OUT-, R_L	300			Ω
Load capacitance at OUT+ and/or OUT-, C_L			100	pF
MSTR CLK frequency (see Note 4)		5	10.368	MHz
Analog input amplifier common mode input voltage (see Note 5)			± 1.5	V
A/D or D/A conversion rate			25	kHz
Operating free-air temperature range, T_A	TLC32047C	0	70	$^{\circ}\text{C}$
	TLC32047I	-40	85	

NOTES: 2. Voltages at analog inputs and outputs, REF, V_{CC+} , and V_{CC-} are with respect to ANLG GND. Voltages at digital inputs and outputs and V_{DD} are with respect to DGTL GND.

- The algebraic convention, in which the least positive (most negative) value is designated minimum, is used in this data manual for logic voltage levels only.
- The band-pass switched-capacitor filter (SCF) specifications apply only when the low-pass section SCF clock is 432 kHz and the high-pass section SCF clock is 24 kHz. If the low-pass SCF clock is shifted from 432 kHz, the low-pass roll-off frequency shifts by the ratio of the low-pass SCF clock to 432 kHz. If the high-pass SCF clock is shifted from 24 kHz, the high-pass roll-off frequency shifts by the ratio of the high-pass SCF clock to 24 kHz. Similarly, the low-pass switched-capacitor filter (SCF) specifications apply only when the SCF clock is 432 kHz. If the SCF clock is shifted from 432 kHz, the low-pass roll-off frequency shifts by the ratio of the SCF clock to 432 kHz.
- This range applies when $(IN+ - IN-)$ or $(AUX IN+ - AUX IN-)$ equals ± 6 V.

3.3 Electrical Characteristics Over Recommended Operating Free-Air Temperature Range, $V_{CC+} = 5$ V, $V_{CC-} = -5$ V, $V_{DD} = 5$ V (Unless Otherwise Noted)

3.3.1 Total Device, MSTR CLK Frequency = 5.184 MHz, Outputs Not Loaded

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V_{OH}	High-level output voltage	$V_{DD} = 4.75$ V, $I_{OH} = -300$ μA	2.4			V
V_{OL}	Low-level output voltage	$V_{DD} = 4.75$ V, $I_{OL} = 2$ mA			0.4	V
I_{CC+}	Supply current from V_{CC+}	TLC32047C			35	mA
		TLC32047I			40	
I_{CC-}	Supply current from V_{CC-}	TLC32047C			-35	mA
		TLC32047I			-40	
I_{DD}	Supply current from V_{DD}				7	mA
V_{ref}	Internal reference output voltage		3		3.3	V
αV_{ref}	Temperature coefficient of internal reference voltage			250		ppm/ $^{\circ}\text{C}$
r_o	Output resistance at REF			100		k Ω

† All typical values are at $T_A = 25^{\circ}\text{C}$.

3.3.2 Power Supply Rejection and Crosstalk Attenuation

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{CC+} or V _{CC-} supply voltage rejection ratio, receive channel	f = 0 to 30 kHz	Idle channel, supply signal at 200 mV p-p measured at DR (ADC output)	30			dB
	f = 30 kHz to 50 kHz		45			
V _{CC+} or V _{CC-} supply voltage rejection ratio, transmit channel (single-ended)	f = 0 to 30 kHz	Idle channel, supply signal at 200 mV p-p measured at OUT+	30			dB
	f = 30 kHz to 50 kHz		45			
Crosstalk attenuation, transmit-to-receive (single-ended)			80			dB

† All typical values are at T_A = 25°C.

3.3.3 Serial Port

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	I _{OH} = -300 μA	2.4			V
V _{OL}	Low-level output voltage	I _{OL} = 2 mA			0.4	V
I _I	Input current				±10	μA
I _I	Input current, DATA-DR/CONTROL				±100	μA
C _i	Input capacitance			15		pF
C _o	Output capacitance			15		pF

† All typical values are at T_A = 25°C.

3.3.4 Receive Amplifier Input

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
A/D converter offset error (filters in)				10	70	mV
CMRR	Common-mode rejection ratio at IN+, IN-, or AUX IN+, AUX IN-	See Note 6		55		dB
r _i	Input resistance at IN+, IN- or AUX IN+, AUX IN-, REF			100		kΩ

† All typical values are at T_A = 25°C.

NOTE 6: The test condition is a 0-dBm, 1-kHz input signal with a 24-kHz conversion rate.

3.3.5 Transmit Filter Output

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OO}	Output offset voltage at OUT+ or OUT- (single-ended relative to ANLG GND)			15	80	mV
V _{OM}	Maximum peak output voltage swing across R _L at OUT+ or OUT- (single-ended)	R _L ≥ 300 Ω, Offset voltage = 0	±3			V
	Maximum peak output voltage swing between OUT+ and OUT- (differential output)	R _L ≥ 600 Ω,	±6			V

† All typical values are at T_A = 25°C.

3.3.6 Receive and Transmit Channel System Distortion, SCF Clock Frequency = 432kHz (see Note 7)

PARAMETER		TEST CONDITIONS	MIN	TYPT†	MAX	UNIT
Attenuation of second harmonic of A/D input signal	single-ended	$V_I = -0.1 \text{ dB to } -24 \text{ dB}$	70		dB	
	differential		62	70		
Attenuation of third and higher harmonics of A/D input signal	single-ended		65		dB	
	differential		57	65		
Attenuation of second harmonic of D/A input signal	single-ended		$V_I = -0 \text{ dB to } -24 \text{ dB}$	70		dB
	differential			62	70	
Attenuation of third and higher harmonics of D/A input signal	single-ended	65		dB		
	differential	57			65	

† All typical values are at $T_A = 25^\circ\text{C}$.

3.3.7 Receive Channel Signal-to-Distortion Ratio (see Note 7)

PARAMETER	TEST CONDITIONS	$A_V = 1 \text{ V/V}^\ddagger$		$A_V = 2 \text{ V/V}^\ddagger$		$A_V = 4 \text{ V/V}^\ddagger$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
A/D channel signal-to-distortion ratio	$V_I = -6 \text{ dB to } -0.1 \text{ dB}$	56		§		§		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	56		56		§		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	53		56		56		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	47		53		56		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	41		47		53		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	35		41		47		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	29		35		41		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	23		29		35		
$V_I = -54 \text{ dB to } -48 \text{ dB}$	17		23		29			

‡ A_V is the programmable gain of the input amplifier.

§ Measurements under these conditions are unreliable due to overrange and signal clipping.

NOTE 7: The test condition is a 1-kHz input signal with a 24-kHz conversion rate. The load impedance for the DAC is 600 Ω . Input and output voltages are referred to V_{ref} .

3.3.8 Transmit Channel Signal-to-Distortion Ratio (see Note 7)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
D/A channel signal-to-distortion ratio	$V_I = -6 \text{ dB to } -0.1 \text{ dB}$	58		dB
	$V_I = -12 \text{ dB to } -6 \text{ dB}$	58		
	$V_I = -18 \text{ dB to } -12 \text{ dB}$	56		
	$V_I = -24 \text{ dB to } -18 \text{ dB}$	50		
	$V_I = -30 \text{ dB to } -24 \text{ dB}$	44		
	$V_I = -36 \text{ dB to } -30 \text{ dB}$	38		
	$V_I = -42 \text{ dB to } -36 \text{ dB}$	32		
	$V_I = -48 \text{ dB to } -42 \text{ dB}$	26		
	$V_I = -54 \text{ dB to } -48 \text{ dB}$	20		

NOTE 7: The test condition is a 1-kHz input signal with a 24-kHz conversion rate. The load impedance for the DAC is 600 Ω . Input and output voltages are referred to V_{ref} .

3.3.9 Receive and Transmit Gain and Dynamic Range (see Note 8)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
Transmit gain tracking error	$V_O = -48 \text{ dB to } 0 \text{ dB}$ signal range	± 0.05	± 0.25		dB
Receive gain tracking error	$V_I = -48 \text{ dB to } 0 \text{ dB}$ signal range	± 0.05	± 0.25		dB

NOTE 8: Gain tracking is relative to the absolute gain at 1 kHz and 0 dB (0 dB relative to V_{ref}).

3.3.10 Receive Channel Band-Pass Filter Transfer Function, SCF $f_{clock} = 432 \text{ kHz}$, Input (IN+ – IN–) is a $\pm 3\text{-V}$ Sine Wave‡ (see Note 9)

PARAMETER	TEST CONDITION	FREQUENCY	ADJUSTMENT	MIN	TYP†	MAX	UNIT
Filter gain	Input signal reference is 0 dB	$f \leq 150 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-33	-29	-25	dB
		$f = 300 \text{ Hz}$	$K1 \times -0.26 \text{ dB}$	-4	-2	-1	
		$f = 450 \text{ Hz to } 9300 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	
		$f = 9300 \text{ Hz to } 9900 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		$f = 9900 \text{ Hz to } 10950 \text{ Hz}$	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		$f = 11.4 \text{ kHz}$	$K1 \times 2.3 \text{ dB}$		-2	-0.5	
		$f = 12 \text{ kHz}$	$K1 \times 2.7 \text{ dB}$		-16	-14	
		$f \geq 13.2 \text{ kHz}$	$K1 \times 3.2 \text{ dB}$			-40	
		$f \geq 15 \text{ kHz}$	$K1 \times 0 \text{ dB}$			-60	

† All typical values are at $T_A = 25^\circ\text{C}$.

‡ The MIN, TYP, and MAX specifications are given for a 432-kHz SCF clock frequency. A slight error in the 432-kHz SCF can result from inaccuracies in the MSTR CLK frequency, resulting from crystal frequency tolerances. If this frequency error is less than 0.25%, the ADJUSTMENT ADDEND should be added to the MIN, TYP, and MAX specifications, where $K1 = 100 \times [(\text{SCF frequency} - 432 \text{ kHz})/432 \text{ kHz}]$. For errors greater than 0.25%, see Note 9.

NOTE 9: The filter gain outside of the pass band is measured with respect to the gain at 1 kHz. The filter gain within the pass band is measured with respect to the average gain within the pass band. The pass bands are 450 Hz to 10.95 kHz and 0 to 10.95 kHz for the band-pass and low-pass filters, respectively. For switched-capacitor filter clocks at frequencies other than 432 kHz, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 432 kHz.

3.3.11 Receive and Transmit Channel Low-Pass Filter Transfer Function, SCF $f_{\text{clock}} = 432 \text{ kHz}$ (see Note 9)

PARAMETER	TEST CONDITION	FREQUENCY RANGE	ADJUSTMENT ADDEND [‡]	MIN	TYP [†]	MAX	UNIT
Filter gain	Input signal reference is 0 dB	f = 0 Hz to 9300 Hz	$K1 \times 0 \text{ dB}$	-0.25	0	0.25	dB
		f = 9300 Hz to 9900 Hz	$K1 \times 0 \text{ dB}$	-0.3	0	0.3	
		f = 9900 Hz to 10950 Hz	$K1 \times 0 \text{ dB}$	-0.5	0	0.5	
		f = 11.4 kHz	$K1 \times 2.3 \text{ dB}$	-5	-2	-0.5	
		f = 12 kHz	$K1 \times 2.7 \text{ dB}$		-16	-14	
		f \geq 13.2 kHz	$K1 \times 3.2 \text{ dB}$			-40	
		f \geq 15 kHz	$K1 \times 0 \text{ dB}$			-60	

[†] All typical values are at $T_A = 25^\circ\text{C}$.

[‡] The MIN, TYP, and MAX specifications are given for a 432-kHz SCF clock frequency. A slight error in the 432-kHz SCF may result from inaccuracies in the MSTR CLK frequency, resulting from crystal frequency tolerances. If this frequency error is less than 0.25%, the ADJUSTMENT ADDEND should be added to the MIN, TYP, and MAX specifications, where $K1 = 100 \times [(SCF \text{ frequency} - 432 \text{ kHz})/432 \text{ kHz}]$. For errors greater than 0.25%, see Note 9.

NOTE 9: The filter gain outside of the pass band is measured with respect to the gain at 1 kHz. The filter gain within the pass band is measured with respect to the average gain within the pass band. The pass bands are 450 Hz to 10.95 kHz and 0 to 10.95 kHz for the band-pass and low-pass filters, respectively. For switched-capacitor filter clocks at frequencies other than 432 kHz, the filter response is shifted by the ratio of switched-capacitor filter clock frequency to 432 kHz.

3.4 Operating Characteristics Over Recommended Operating Free-Air Temperature Range, $V_{CC+} = 5 \text{ V}$, $V_{CC-} = -5 \text{ V}$, $V_{DD} = 5 \text{ V}$

3.4.1 Receive and Transmit Noise (Measurement Includes Low-Pass and Band-Pass Switched-Capacitor Filters)

PARAMETER		TEST CONDITIONS	MIN	TYP [†]	MAX	UNIT
Transmit noise	broadband with (sin x)/x	DX = input = 00000000000000, constant input code		280	500	$\mu\text{V rms}$
	broadband without (sin x)/x			250	450	
	0 to 12 kHz with (sin x)/x			250	400	
	0 to 12 kHz without (sin x)/x			240	400	
Receive noise (see Note 10)		Inputs grounded, gain = 1		300	500	$\mu\text{V rms}$
				18		dBrnc0

[†] All typical values are at $T_A = 25^\circ\text{C}$.

NOTE 10: The noise is computed by statistically evaluating the digital output of the A/D converter.

3.5 Timing Requirements

3.5.1 Serial Port Recommended Input Signals

PARAMETER		MIN	MAX	UNIT
$t_c(\text{MCLK})$	Master clock cycle time	95		ns
$t_r(\text{MCLK})$	Master clock rise time		10	ns
$t_f(\text{MCLK})$	Master clock fall time		10	ns
	Master clock duty cycle	25%	75%	
	$\overline{\text{RESET}}$ pulse duration (see Note 11)	800		ns
$t_{su}(\text{DX})$	DX setup time before SCLK↓	20		ns
$t_h(\text{DX})$	DX hold time after SCLK↓	$t_c(\text{SCLK})/4$		ns

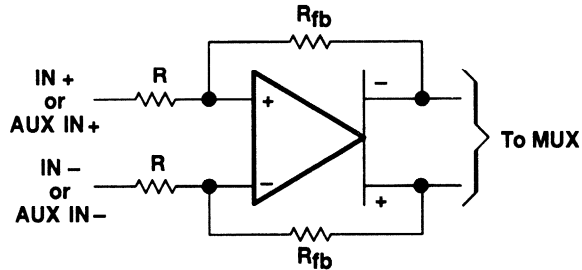
NOTE 11: $\overline{\text{RESET}}$ pulse duration is the amount of time that the reset pin is held below 0.8 V after the power supplies have reached their recommended values.

3.5.2 Serial Port – AIC Output Signals, $C_L = 30$ pF for SHIFT CLK Output, $C_L = 15$ pF For All Other Outputs

PARAMETER		MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$	Shift clock (SCLK) cycle time	380			ns
$t_f(\text{SCLK})$	Shift clock (SCLK) fall time		3	8	ns
$t_r(\text{SCLK})$	Shift clock (SCLK) rise time		3	8	ns
	Shift clock (SCLK) duty cycle	45		55	%
$t_d(\text{CH-FL})$	Delay from SCLK↑ to $\overline{\text{FSR}}/\text{FSX}/\overline{\text{FSD}}\downarrow$		30		ns
$t_d(\text{CH-FH})$	Delay from SCLK↑ to $\overline{\text{FSR}}/\text{FSX}/\overline{\text{FSD}}\uparrow$		35	90	ns
$t_d(\text{CH-DR})$	DR valid after SCLK↑			90	ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\downarrow$ in word mode			90	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\uparrow$ in word mode			90	ns
$t_f(\text{EODX})$	$\overline{\text{EODX}}$ fall time		2	8	ns
$t_f(\text{EODR})$	$\overline{\text{EODR}}$ fall time		2	8	ns
$t_d(\text{CH-EL})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\downarrow$ in byte mode			90	ns
$t_d(\text{CH-EH})$	Delay from SCLK↑ to $\overline{\text{EODX}}/\overline{\text{EODR}}\uparrow$ in byte mode			90	ns
$t_d(\text{MH-SL})$	Delay from MSTR CLK↑ to SCLK↓		65	170	ns
$t_d(\text{MH-SH})$	Delay from MSTR CLK↑ to SCLK↑		65	170	ns

† Typical values are at $T_A = 25^\circ\text{C}$.

4 Parameter Measurement Information



$$R_{fb} = R \text{ for } D6 = 1 \text{ and } D7 = 1$$

$$D6 = 0 \text{ and } D7 = 0$$

$$R_{fb} = 2R \text{ for } D6 = 1 \text{ and } D7 = 0$$

$$R_{fb} = 4R \text{ for } D6 = 0, \text{ and } D7 = 1$$

Figure 4–1. IN+ and IN– Gain Control Circuitry

Table 4–1. Gain Control Table (Analog Input Signal Required for Full-Scale Bipolar A/D Conversion Twos Complement)[†]

INPUT CONFIGURATIONS	CONTROL REGISTER BITS		ANALOG INPUT [‡] §	A/D CONVERSION RESULT
	D6	D7		
Differential configuration Analog input = IN+ – IN– = AUX IN+ – AUX IN–	1	1	$V_{ID} = \pm 6 \text{ V}$	\pm full scale
	0	0	$V_{ID} = \pm 3 \text{ V}$	\pm full scale
	1	0	$V_{ID} = \pm 1.5 \text{ V}$	\pm full scale
Single-ended configuration Analog input = IN+ – ANLG GND = AUX IN+ – ANLG GND	1	1	$V_I = \pm 3 \text{ V}$	\pm half scale
	0	0	$V_I = \pm 3 \text{ V}$	\pm full scale
	1	0	$V_I = \pm 1.5 \text{ V}$	\pm full scale

[†] $V_{CC+} = 5 \text{ V}$, $V_{CC-} = -5 \text{ V}$, $V_{DD} = 5 \text{ V}$

[‡] V_{ID} = Differential Input Voltage, V_I = Input voltage referenced to ground with IN– or AUX IN– connected to ground.

[§] In this example, V_{ref} is assumed to be 3 V. In order to minimize distortion, it is recommended that the analog input not exceed 0.1 dB below full scale.

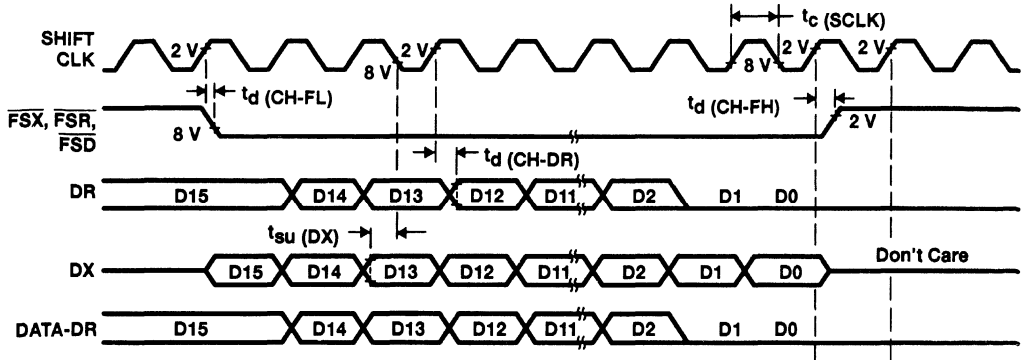


Figure 4–2. Dual-Word (Telephone Interface) Mode Timing

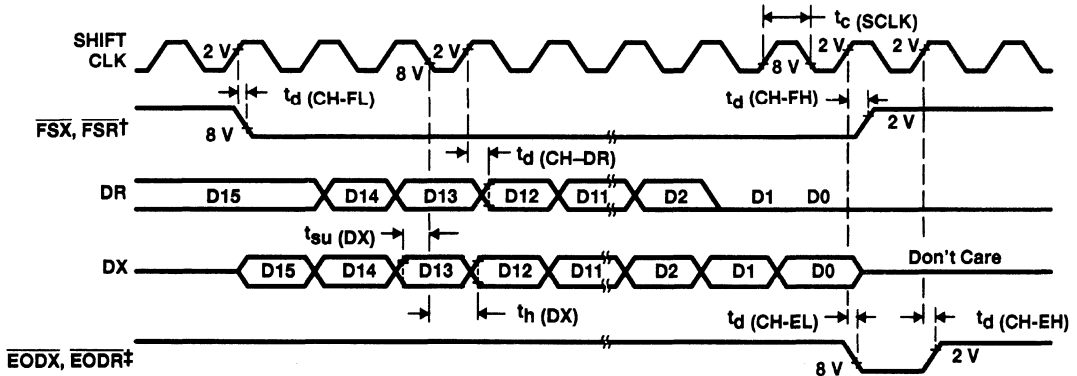


Figure 4–3. Word Timing

† The time between falling edges of $\overline{\text{FSR}}$ is the A/D conversion period and the time between falling edges of $\overline{\text{FSX}}$ is the D/A conversion period.

‡ In the word format, $\overline{\text{EODX}}$ and $\overline{\text{EODR}}$ go low to signal the end of a 16-bit data word to the processor. The word-cycle is 20 shift-clocks wide, giving a four-clock period setup time between data words.

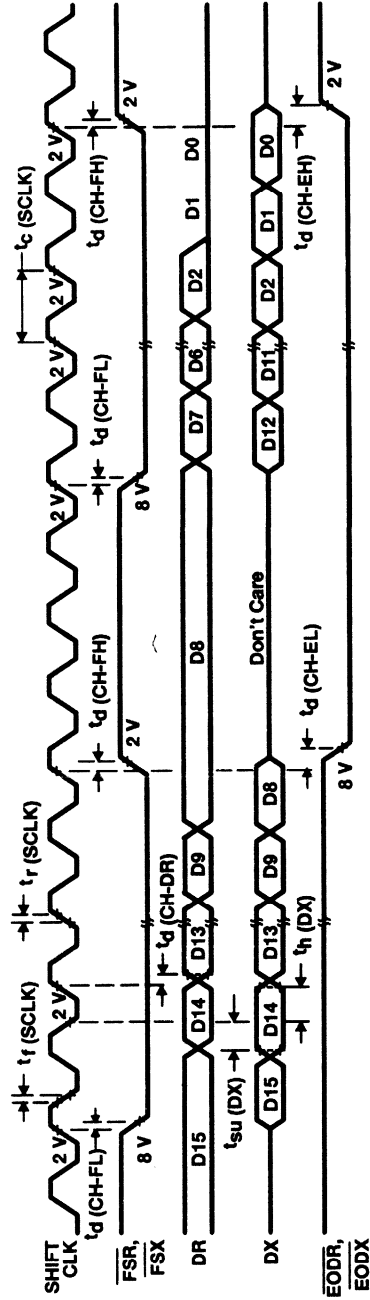


Figure 4-4. Byte-Mode Timing

† The time between falling edges of FSR is the A/D conversion period, and the time between falling edges of FSX is the D/A conversion period.
 ‡ In the byte mode, when EODX or EODR is high, the first byte is transmitted or received, and when these signals are low, the second byte is transmitted or received. Each byte-cycle is 12 shift-clocks long, allowing for a four-shift-clock setup time between byte transmissions.

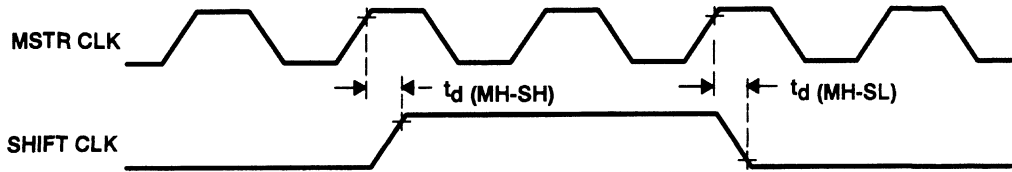


Figure 4-5. Shift-Clock Timing

4.1 TMS32047 – Processor Interface

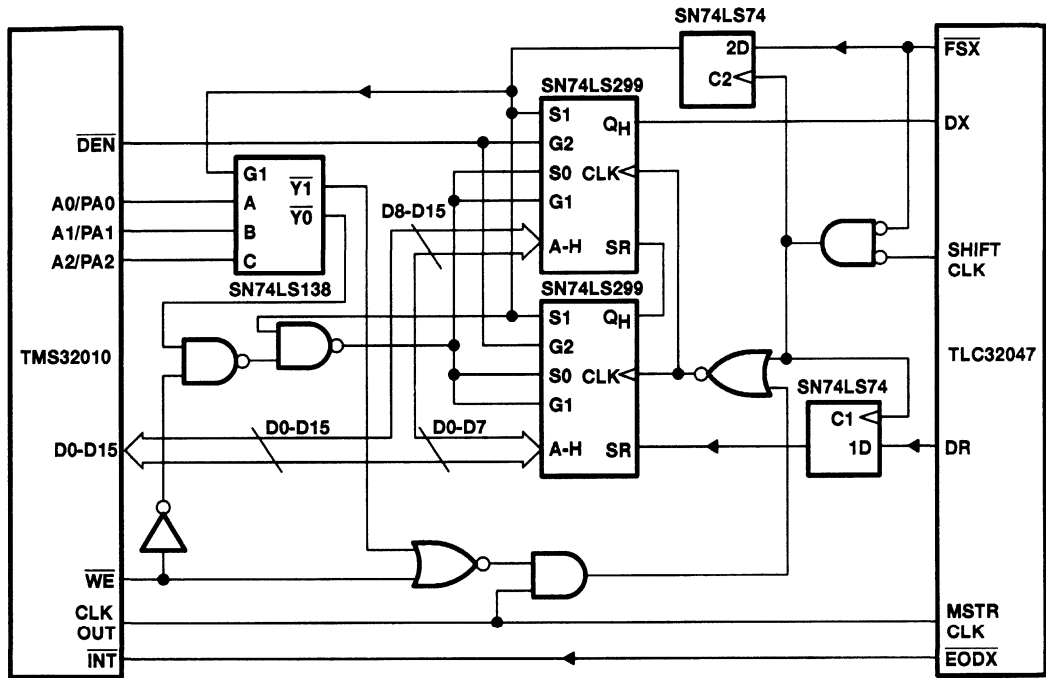


Figure 4-6. TMS32010/TMS320C15-TLC32047 Interface Circuit

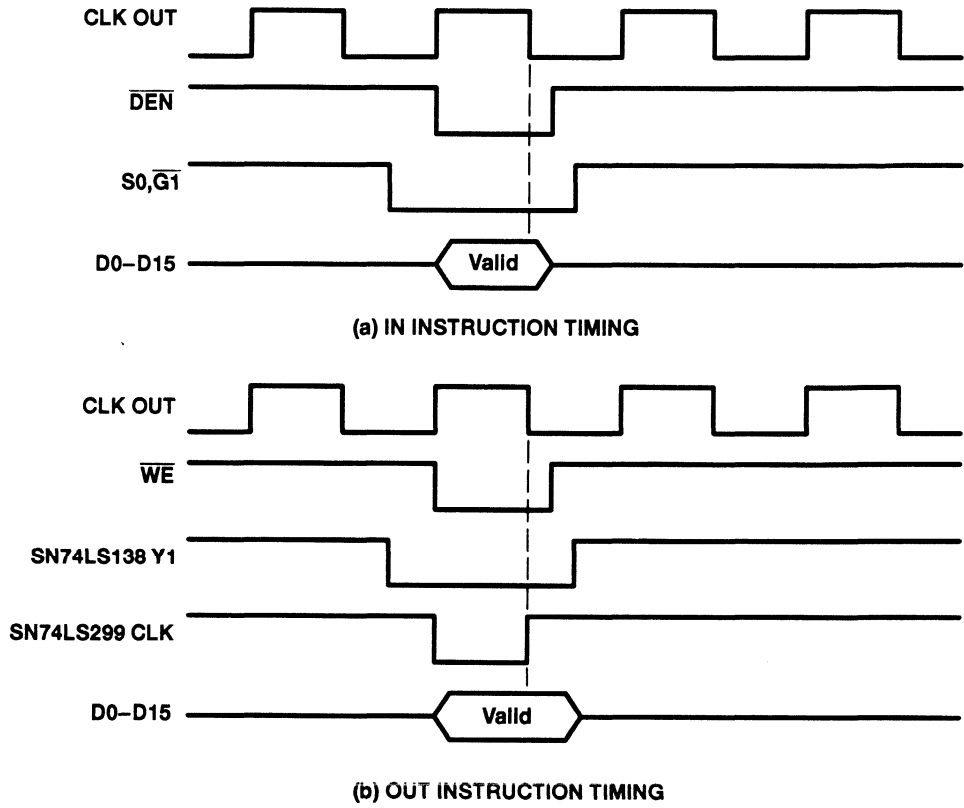


Figure 4-7. TMS32010/TMS320C15-TLC32047 Interface Timing

5 Typical Characteristics

**D/A AND A/D LOW-PASS FILTER
RESPONSE SIMULATION**

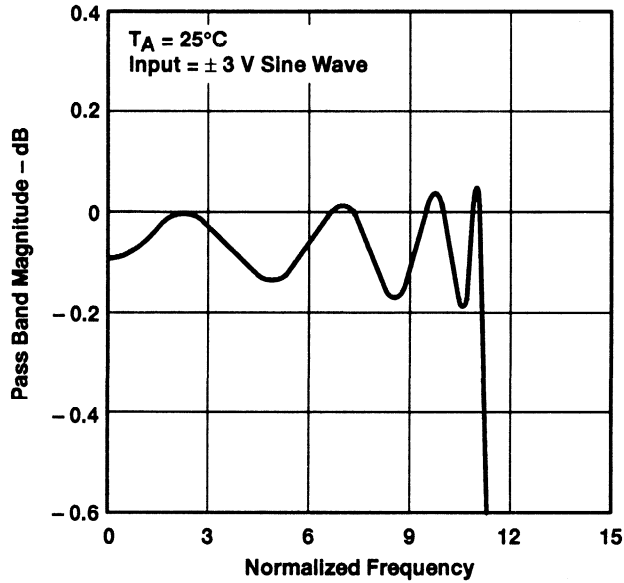


Figure 5-1

**D/A AND A/D LOW-PASS FILTER
RESPONSE SIMULATION**

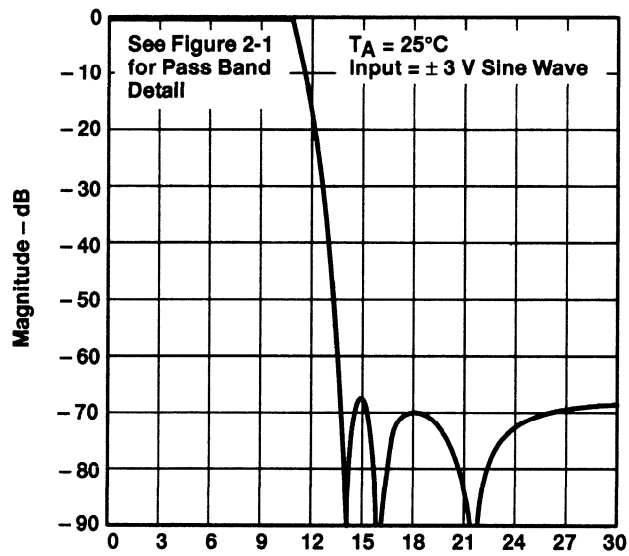


Figure 5-2

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{432}$

D/A AND A/D LOW-PASS GROUP DELAY

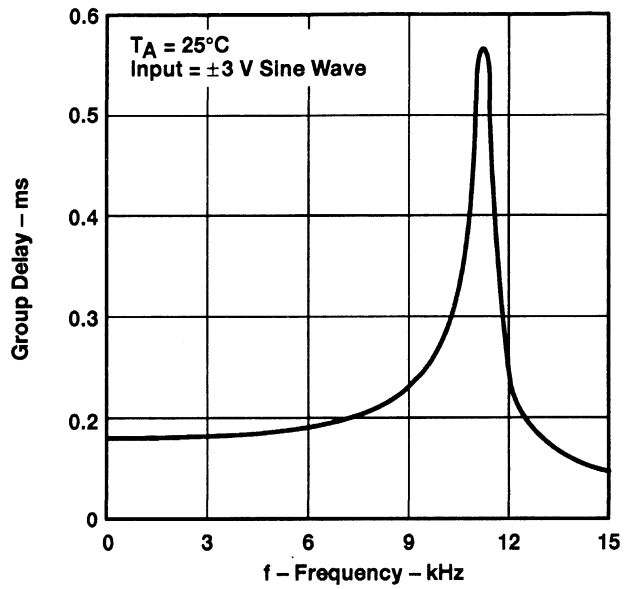


Figure 5-3

A/D BAND-PASS RESPONSE

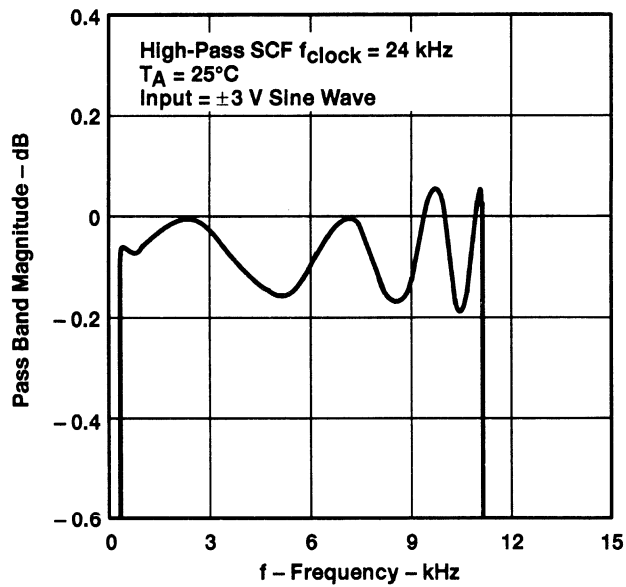


Figure 5-4

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} (\text{kHz})}{432}$

A/D BAND-PASS FILTER RESPONSE SIMULATION

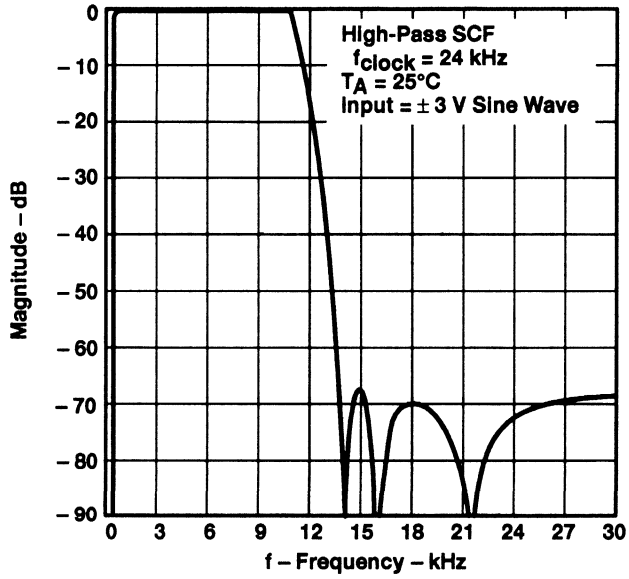


Figure 5-5

A/D BAND-PASS FILTER GROUP DELAY

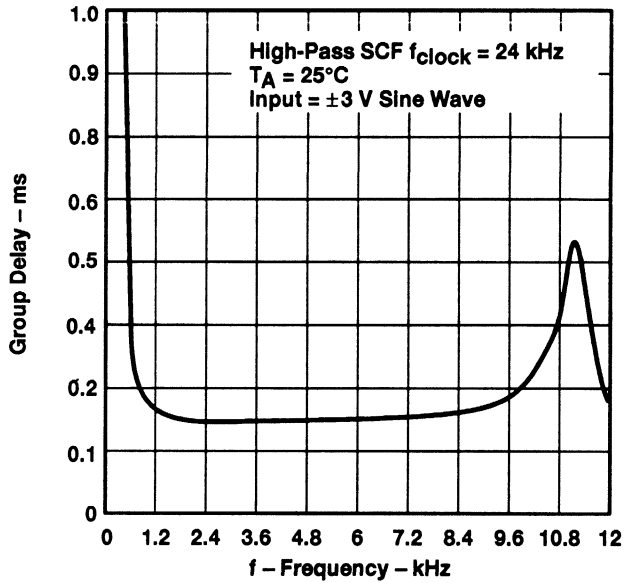


Figure 5-6

NOTE : Absolute Frequency (kHz) =
$$\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{432}$$

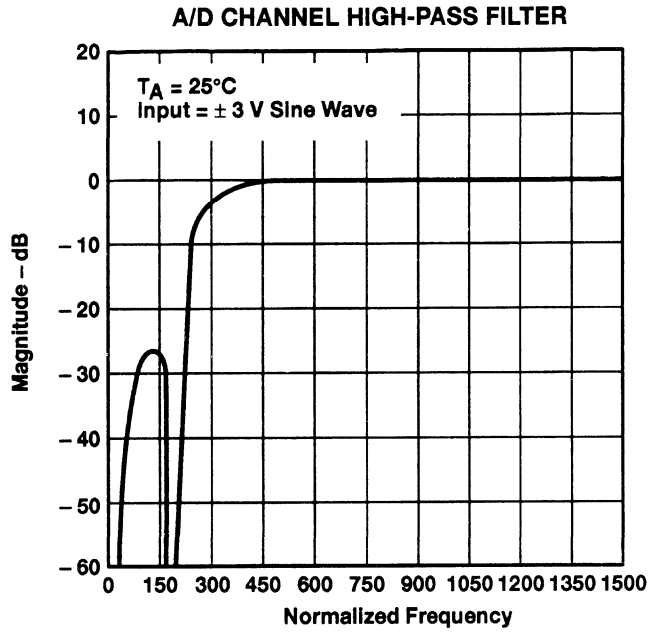


Figure 5-7

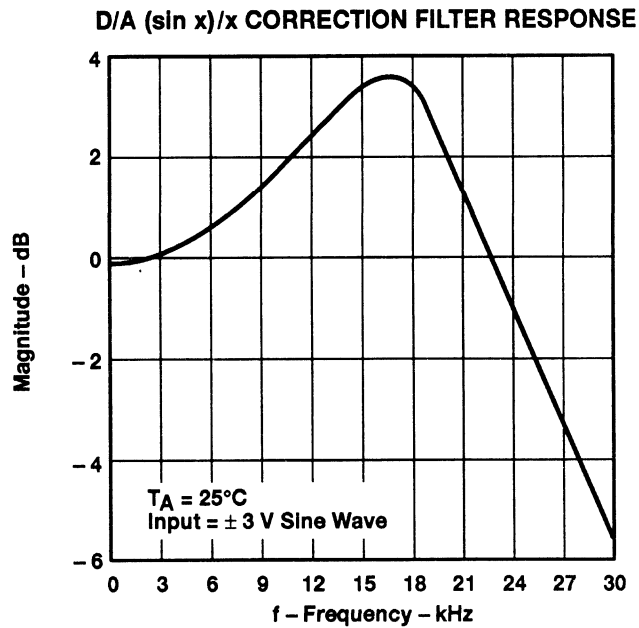


Figure 5-8

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{432}$

D/A (sin x)/x CORRECTION FILTER RESPONSE

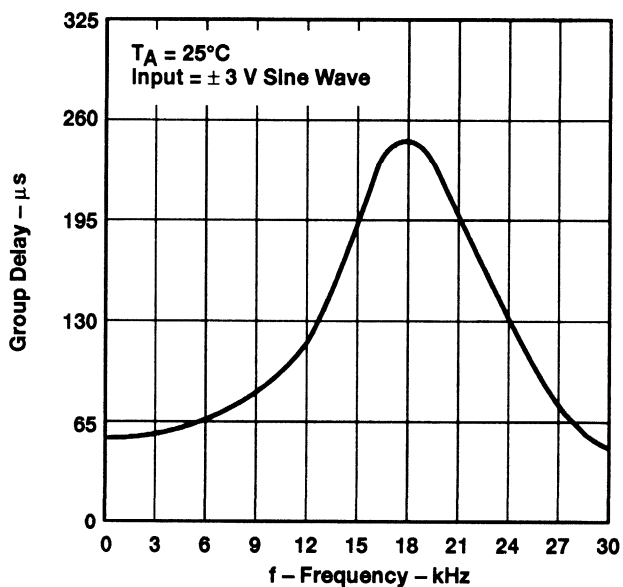


Figure 5-9

D/A (sin x)/x CORRECTION ERROR

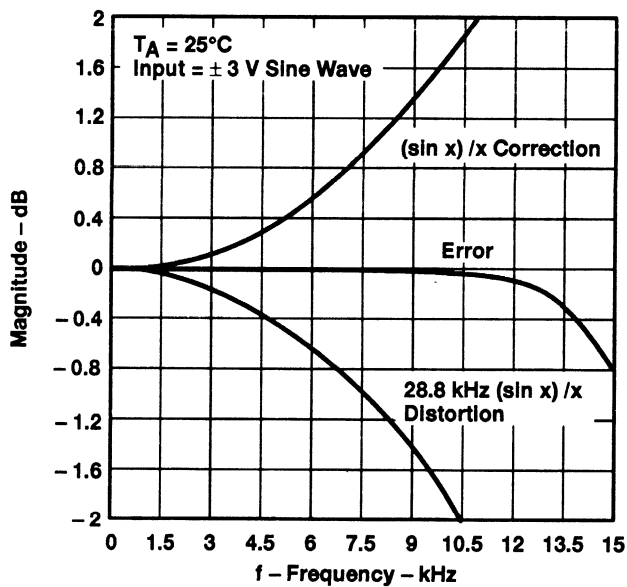


Figure 5-10

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{SCF } f_{\text{clock}} \text{ (kHz)}}{432}$

A/D BAND-PASS GROUP DELAY

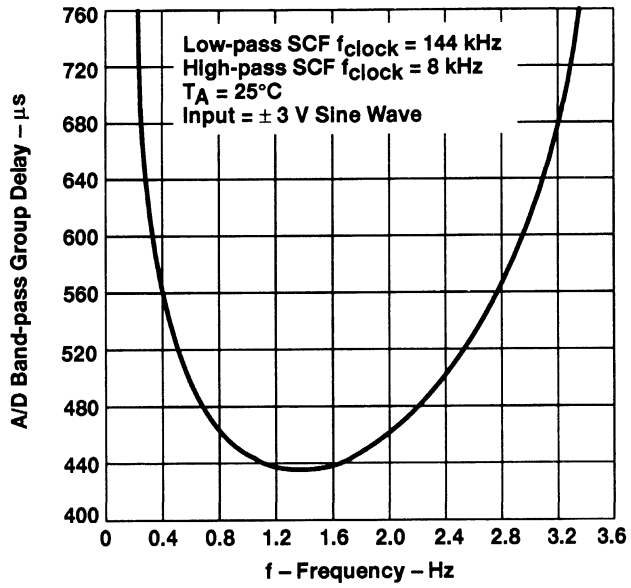


Figure 5-11

D/A LOW-PASS GROUP DELAY

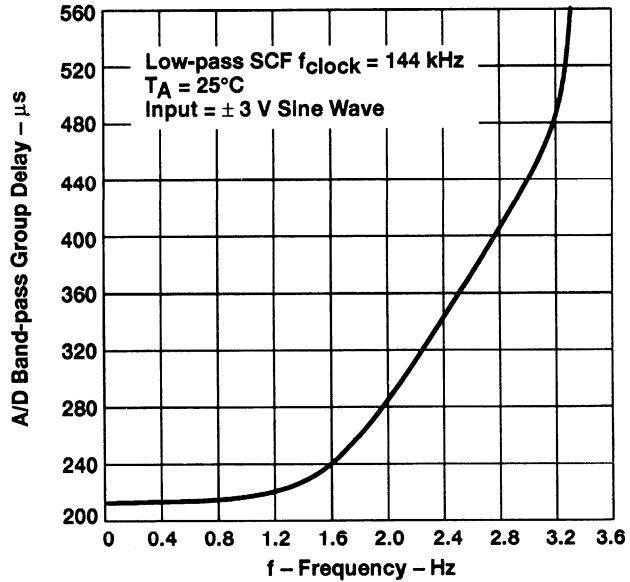


Figure 5-12

**A/D SIGNAL-TO-DISTORTION RATIO
vs
INPUT SIGNAL**

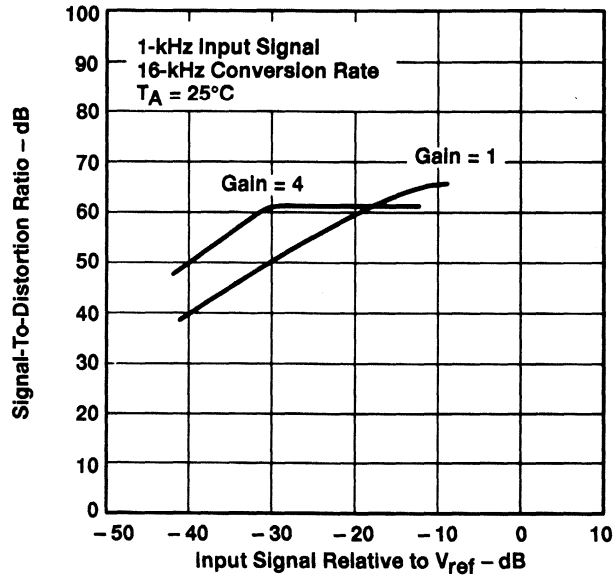


Figure 5-13

**A/D GAIN TRACKING
(GAIN RELATIVE TO GAIN AT 0-dB INPUT SIGNAL)**

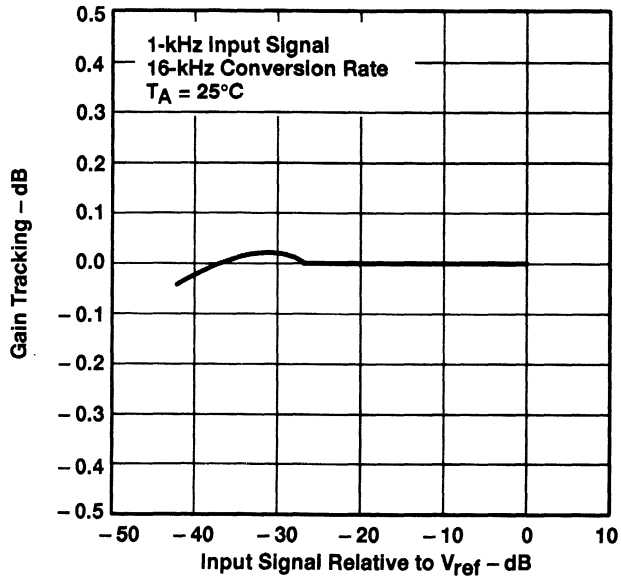


Figure 5-14

**D/A CONVERTER SIGNAL-TO-DISTORTION RATIO
vs
INPUT SIGNAL**

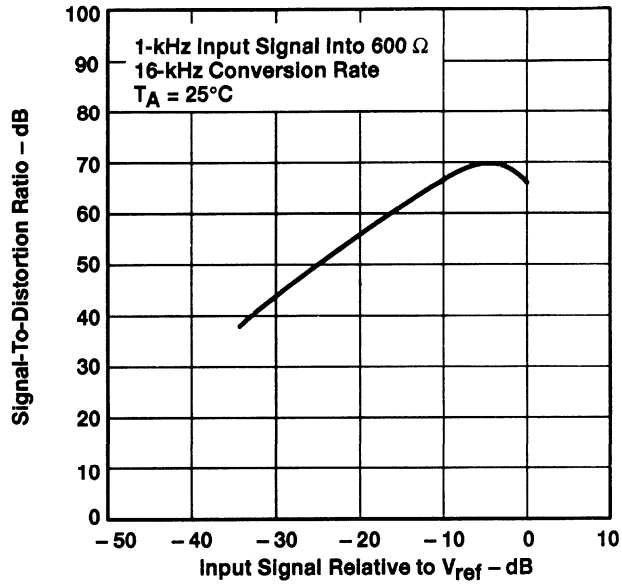


Figure 5-15

**D/A GAIN TRACKING (GAIN RELATIVE TO GAIN
AT 0-dB INPUT SIGNAL)**

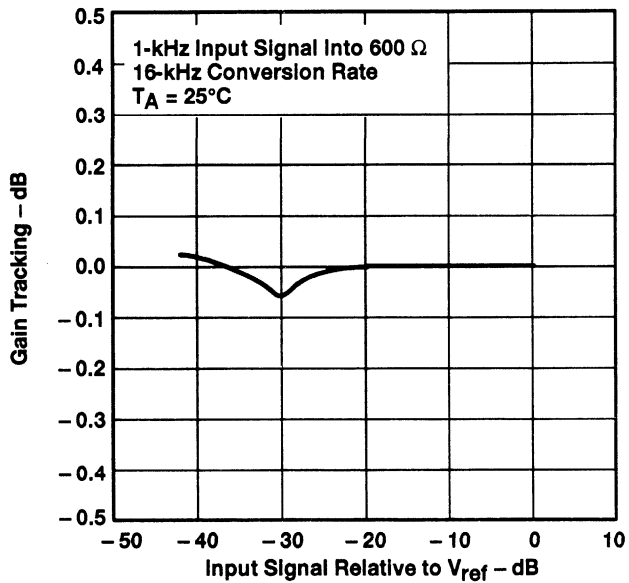


Figure 5-16

**A/D SECOND HARMONIC DISTORTION
vs
INPUT SIGNAL**

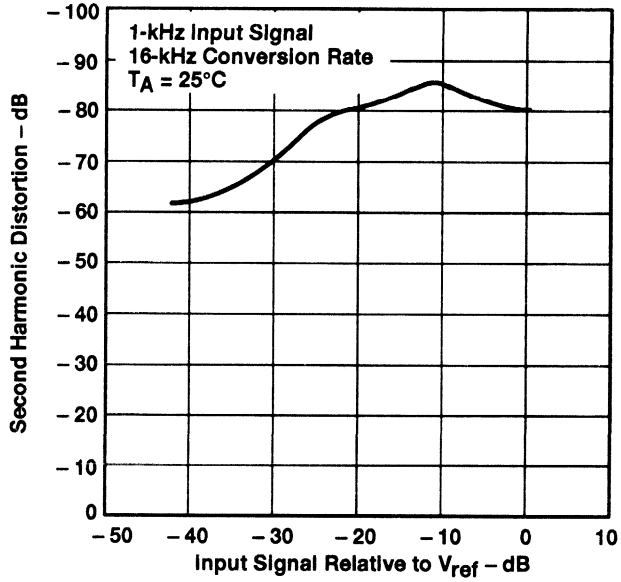


Figure 5-17

**D/A SECOND HARMONIC DISTORTION
vs
INPUT SIGNAL**

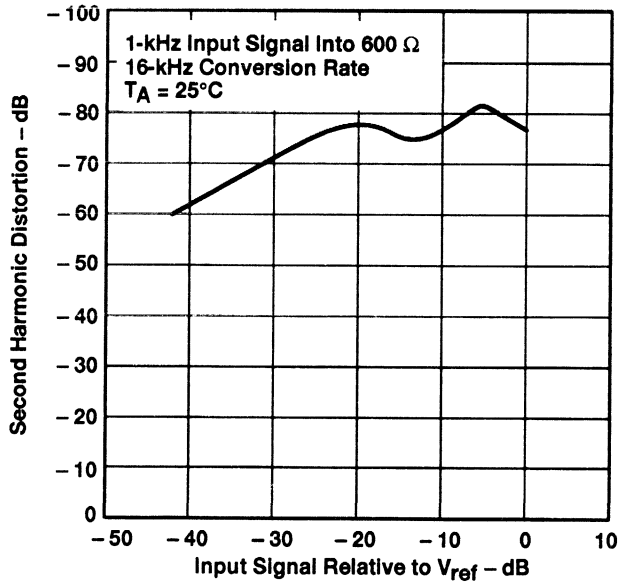


Figure 5-18

**A/D THIRD HARMONIC DISTORTION
vs
INPUT SIGNAL**

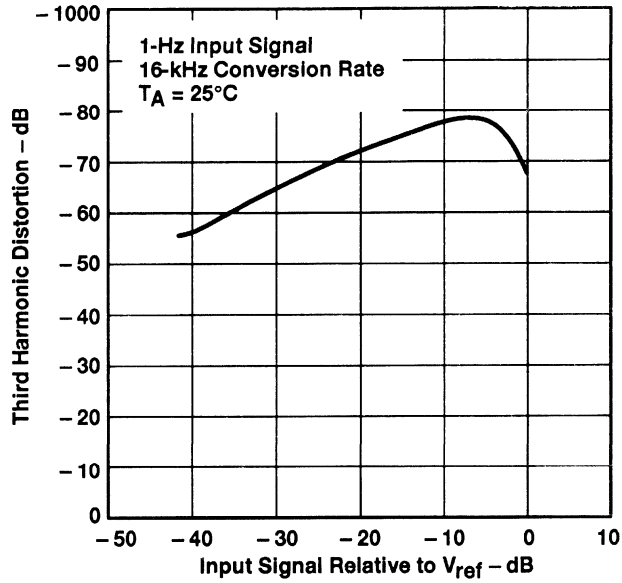


Figure 5-19

**D/A THIRD HARMONIC DISTORTION
vs
INPUT SIGNAL**

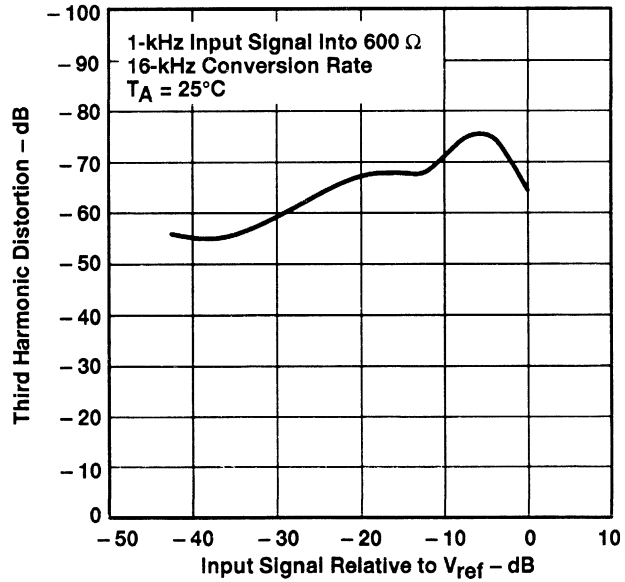


Figure 5-20

6 Application Information

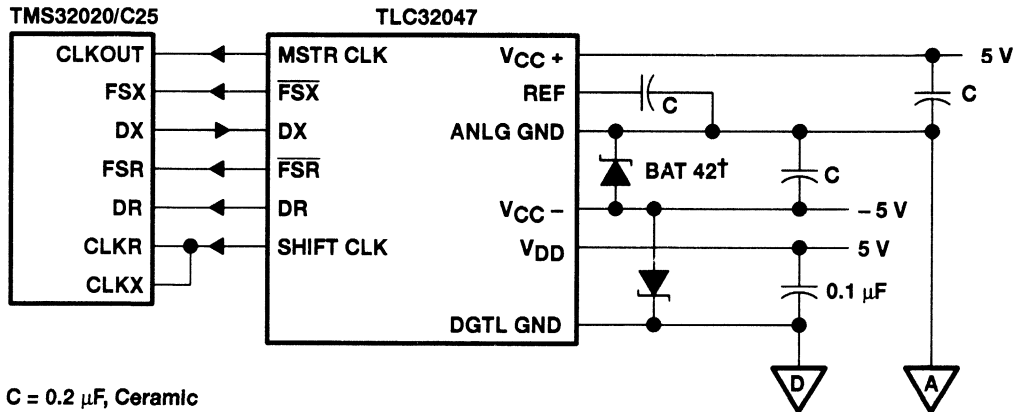
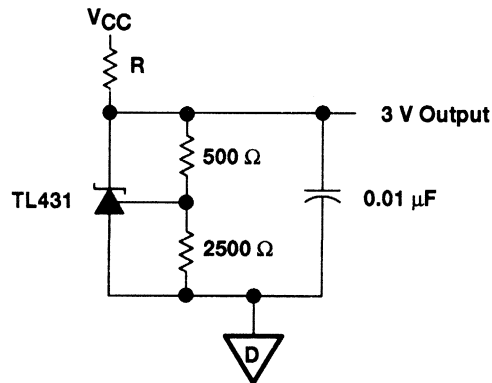


Figure 6-1. AIC Interface to the TMS32020/C25 Showing Decoupling Capacitors and Schottky Diode†

† Thomson Semiconductors



FOR: $V_{CC} = 12 \text{ V}$, $R = 7200 \Omega$
 $V_{CC} = 10 \text{ V}$, $R = 5600 \Omega$
 $V_{CC} = 0 \text{ V}$, $R = 1600 \Omega$

Figure 6-2. External Reference Circuit for TLC32047

TLC320AC01C ***Data Manual***

Single-Supply Analog Interface Circuit



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1 Introduction

The TLC320AC01[†] analog interface circuit (AIC) is an audio-band processor that provides an analog-to-digital and digital-to-analog input/output interface system on a single monolithic CMOS chip. This device integrates a band-pass switched-capacitor antialiasing input filter, a 14-bit-resolution analog-to-digital converter (ADC), a 14-bit-resolution digital-to-analog converter (DAC), a low-pass switched-capacitor output-reconstruction filter, $(\sin x)/x$ compensation, and a serial port for data and control transfers.

The internal circuit configuration and performance parameters are determined by reading control information into the eight available data registers. The register data sets up the device for a given mode of operation and application.

The major functions of the TLC320AC01 are:

1. To convert audio-signal data to digital format by the ADC channel
2. To provide the interface and control logic to transfer data between its serial input and output terminals and a digital signal processor (DSP) or microprocessor
3. To convert received digital data back to an audio signal through the DAC channel

The antialiasing input low-pass filter is a switched-capacitor filter with a sixth-order elliptic characteristic. The high-pass filter is a single-pole filter to preserve low-frequency response as the low-pass filter cutoff is adjusted. There is a three-pole continuous-time filter that precedes this filter to eliminate any aliasing caused by the filter clock signal.

The output-reconstruction switched-capacitor filter is a sixth-order elliptic transitional low-pass filter followed by a second-order $(\sin x)/x$ correction filter. This filter is followed by a three-pole continuous-time filter to eliminate images of the filter clock signal.

The TLC320AC01 consists of two signal-processing channels, an ADC channel and a DAC channel, and the associated digital control. The two channels operate synchronously; data reception at the DAC channel and data transmission from the ADC channel occur during the same time interval. The data transfer is in 2s-complement format.

There are three basic modes of operation available: the stand-alone analog-interface mode, the master-slave mode, and the linear-codec mode. In the stand-alone mode, the TLC320AC01 generates the shift clock and frame synchronization for the data transfers and is the only AIC used. The master-slave mode has one TLC320AC01 as the master that generates the master-shift clock and frame synchronization; the remaining AICs are slaves to these signals. In the linear-codec mode, the shift clock and the frame-synchronization signals are externally generated and the timing can be any of the standard codec-timing patterns.

Typical applications for this device include modems, speech processing, analog interface for DSPs, industrial-process control, acoustical-signal processing, spectral analysis, data acquisition, and instrumentation recorders.

The TLC320AC01C is characterized for operation from 0°C to 70°C.

[†] The TLC320AC01 is functionally equivalent to the TLC320AC02 and differs in the electrical specifications as shown in Appendix C.

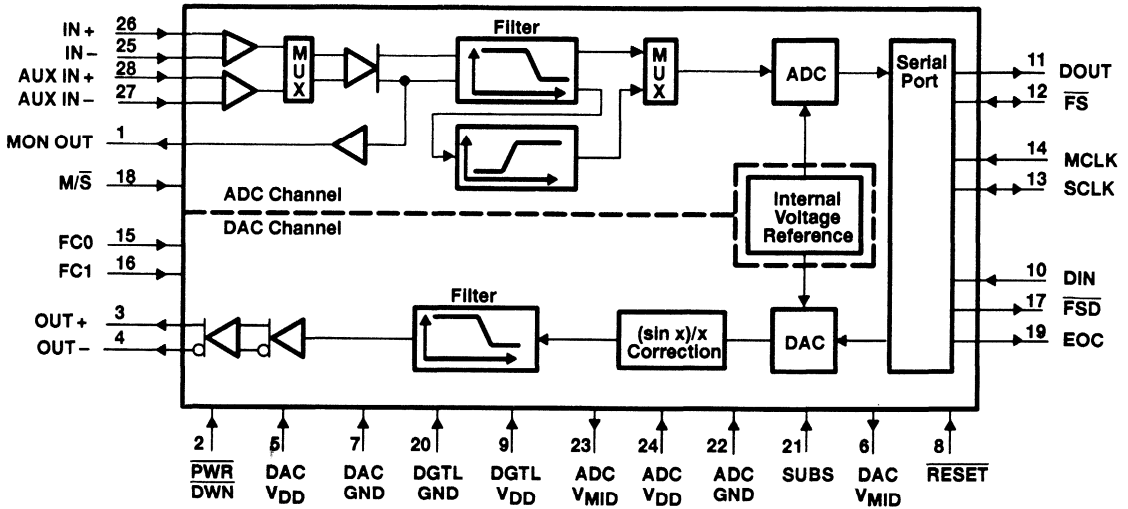
1.1 Features

- General-Purpose Signal-Processing Analog Front End (AFE)
- Single 5-V Power Supply
- Power Dissipation . . . 100 mW Typ
- Signal-to-Distortion Ratio . . . 70 dB Typ
- Programmable Filter Bandwidths (Up to 10.8 kHz) and Synchronous ADC and DAC Sampling
- Serial-Port Interface
- Monitor Output With Programmable Gains of 0 dB, –8 dB, –18 dB, and Squelch
- Two Sets of Differential Inputs With Programmable Gains of 0 dB, 6 dB, 12 dB, and Squelch
- Differential or Single-Ended Analog Output With Programmable Gains of 0 dB, –6 dB, –12 dB, and Squelch
- Differential Outputs Drive 3-V Peak into a 600- Ω Differential Load
- Differential Architecture Throughout
- 1- μm Advanced LinEPIC™ Process
- 14-Bit Dynamic-Range ADC and DAC
- 2s-Complement Data Format
- Application Report Available†

† Designing with the TLC320AC01 Analog interface for DSPs (SLAA006)

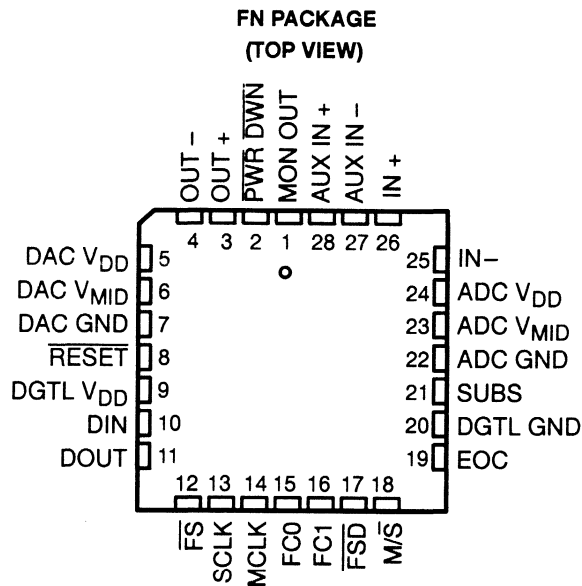
LinEPIC is a trademark of Texas Instruments Incorporated.

1.2 Functional Block Diagram

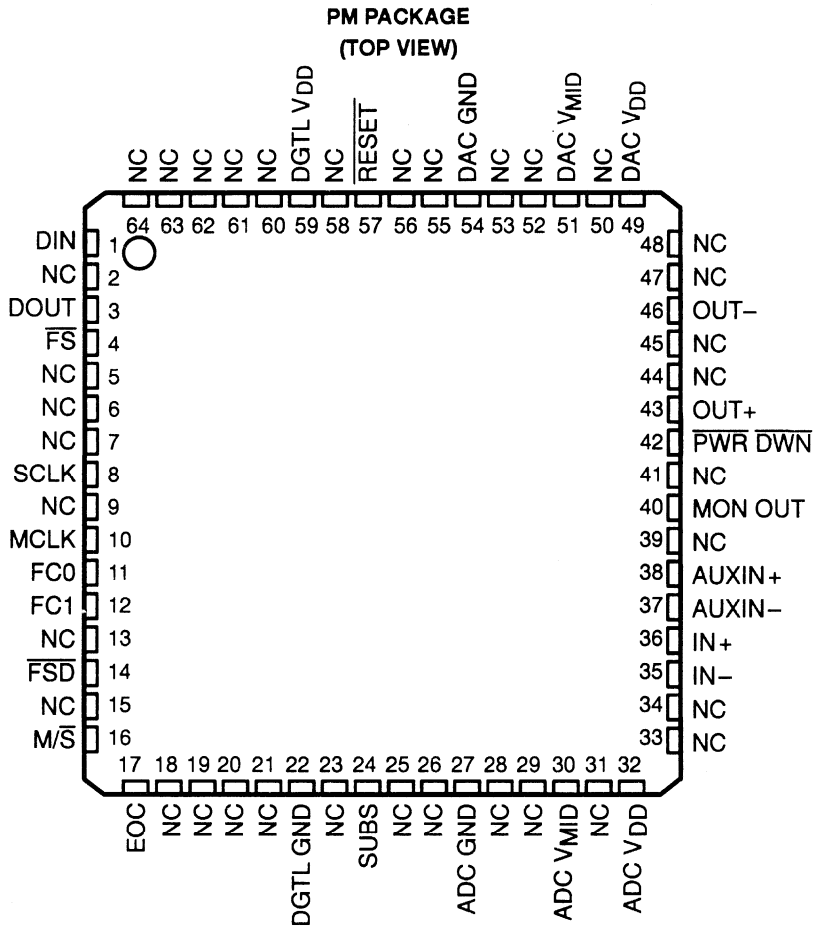


Terminal numbers shown are for the FN package.

1.3 Terminal Assignments



1.3 Terminal Assignments (Continued)



NC – No internal connection

1.4 Terminal Functions

TERMINAL NAME	NO.		I/O	DESCRIPTION
	†	‡		
ADC V _{DD}	24	32	I	Analog supply voltage for the ADC channel
ADC V _{MID}	23	30	O	Midsupply for the ADC channel (requires a bypass capacitor). ADC V _{MID} must be buffered when used as an external reference.
ADC GND	22	27	I	Analog ground for the ADC channel
AUX IN+	28	38	I	Noninverting input to auxiliary analog input amplifier
AUX IN-	27	37	I	Inverting input to auxiliary analog input amplifier
DAC V _{DD}	5	49	I	Digital supply voltage for the DAC channel
DAC V _{MID}	6	51	O	Midsupply for the DAC channel (requires a bypass capacitor). DAC V _{MID} must be buffered when used as an external reference.
DAC GND	7	54	I	Analog ground for the DAC channel
DIN	10	1	I	Data input. DIN receives the DAC input data and command information and is synchronized with SCLK.
DOUT	11	3	O	Data output. DOUT outputs the ADC data results and register read contents. DOUT is synchronized with SCLK.
DGTL V _{DD}	9	59	I	Digital supply voltage for control logic
DGTL GND	20	22	I	Digital ground for control logic
EOC	19	17	O	End-of-conversion output. EOC goes high at the start of the ADC conversion period and low when conversion is complete. EOC remains low until the next ADC conversion period begins and indicates the internal device conversion period.
FC0	15	11	I	Hardware control input. FC0 is used in conjunction with FC1 to request secondary communication and phase adjustments. FC0 should be tied low if it is not used.
FC1	16	12	I	Hardware control input. FC1 is used in conjunction with FC0 to request secondary communication and phase adjustments. FC1 should be tied low if it is not used.
\overline{FS}	12	4	I/O	Frame synchronization. When \overline{FS} goes low, DIN begins receiving data bits and DOUT begins transmitting data bits. In master mode, \overline{FS} is low during the simultaneous 16-bit transmission to DIN and from DOUT. In slave mode, \overline{FS} is externally generated and must be low for one shift-clock period minimum to initiate the data transfer.
FSD	17	14	O	Frame-synchronization delayed output. This active-low output synchronizes a slave device to the frame synchronization timing of the master device. FSD is applied to the slave \overline{FS} input and is the same duration as the master \overline{FS} signal but delayed in time by the number of shift clocks programmed in the FSD register.
IN+	26	36	I	Noninverting input to analog input amplifier
IN-	25	35	I	Inverting input to analog input amplifier
MCLK	14	10	I	The master-clock input drives all the key logic signals of the AIC.
MON OUT	1	40	O	The monitor output allows monitoring of analog input and is a high-impedance output.
M \overline{S}	18	16	I	Master/slave select input. When M \overline{S} is high, the device is the master and when low, it is a slave.

† Terminal numbers shown are for the FN package.

‡ Terminal numbers shown are for the PM package.

1.4 Terminal Functions (Continued)

TERMINAL			I/O	DESCRIPTION
NAME	NO.†	NO.‡		
OUT+	3	43	O	Noninverting output of analog output power amplifier. OUT+ can drive transformer hybrids or high-impedance loads directly in a differential connection or a single-ended configuration with a buffered V_{MID} .
OUT-	4	46	O	Inverting output of analog output power amplifier. OUT- is functionally identical with and complementary to OUT+.
PWR DWN	2	42	I	Power-down input. When $\overline{PWR DWN}$ is taken low, the device is powered down such that the existing internally programmed state is maintained. When $\overline{PWR DWN}$ is brought high, full operation resumes.
\overline{RESET}	8	57	I	Reset input that initializes the internal counters and control registers. \overline{RESET} initiates the serial data communications, initializes all of the registers to their default values, and puts the device in a preprogrammed state. After a low-going pulse on \overline{RESET} , the device registers are initialized to provide a 16-kHz data-conversion rate and 7.2-kHz filter bandwidth for a 10.368-MHz master clock input signal.
SCLK	13	8	I/O	Shift clock. SCLK clocks the digital data into DIN and out of DOUT during the frame-synchronization interval. When configured as an output (M/\overline{S} high), SCLK is generated internally by dividing the master clock signal frequency by four. When configured as an input (M/\overline{S} low), SCLK is generated externally and synchronously to the master clock. This signal clocks the serial data into and out of the device.
SUBS	21	24	I	Substrate connection. SUBS should be tied to ADC GND.

† Terminal numbers shown are for the FN package.

‡ Terminal numbers shown are for the PM package.

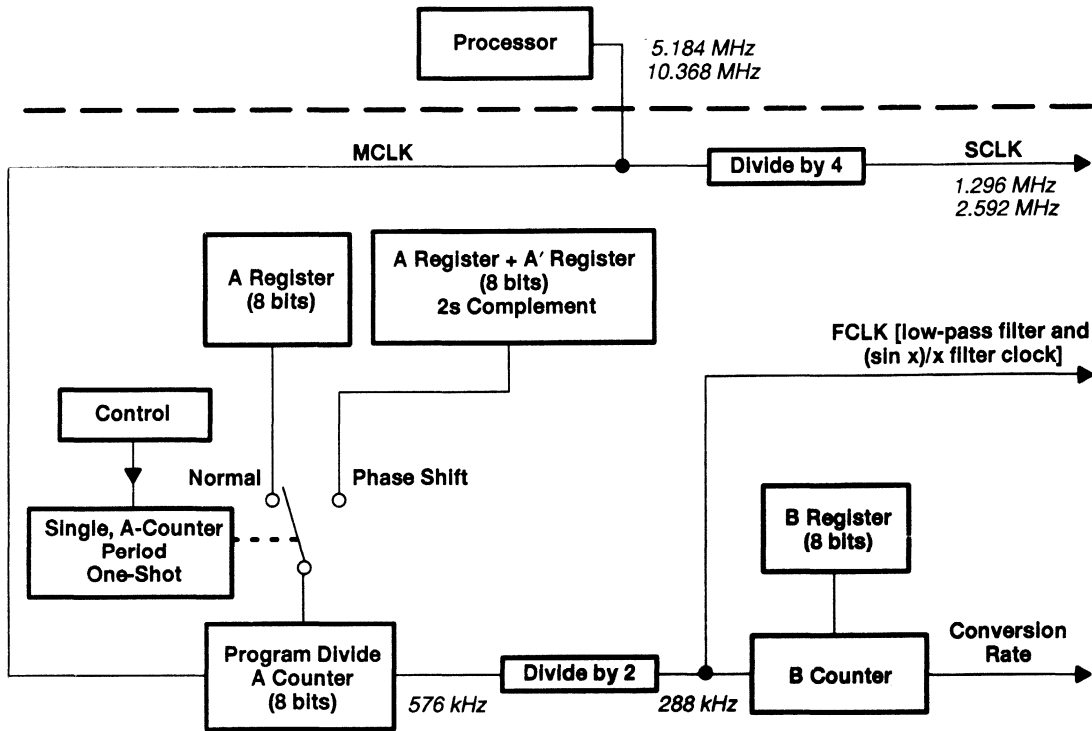


Figure 1-1. Control Flow Diagram

Table 1-1. Operating Frequencies

FCLK (kHz)	LOW-PASS FILTER BANDWIDTH (kHz)	B REGISTER CONTENTS (Program No. of Filter Clocks) (Decimal)	CONVERSION RATE (kHz)	HIGH-PASS POLE FREQUENCY (Hz)
144	3.6	20 (see Note 1)	7.2	36
		18	8	40
		15	9.6	48
		10 (see Note 2)	14.4	72
288	7.2	20 (see Note 1)	14.4	72
		18	16	80
		15	19.2	96
		10 (see Notes 2 and 3)	28.8	144
432	10.8	20 (see Note 1)	21.6	108
		18	24	120
		15 (see Note 3)	28.8	144
		10 (see Notes 2 and 3)	43.2	216

- NOTES:
1. The B register can be programmed for values greater than 20; however, since the sample rate is lower than 7.2 kHz and the internal filter remains at 3.6 kHz, an external antialiasing filter is required.
 2. When the B register is programmed for a value less than 10, the ADC and the DAC conversions are not completed before the next frame-sync signal and the results are in error.
 3. The maximum sampling rate for the ADC channel is 43.2 kHz. The maximum rate for the DAC channel is 25 kHz.

1.5 Register Functional Summary

There are nine data registers that are used as follows:

- Register 0 The No-op register. The 0 address allows phase adjustments to be made without reprogramming a data register.
- Register 1 The A register controls the count of the A counter.
- Register 2 The B register controls the count of the B counter.
- Register 3 The A' register controls the phase adjustment of the sampling period. The adjustment is equal to the register value multiplied by the input master period.
- Register 4 The amplifier gain register controls the gains of the input, output, and monitor amplifiers.
- Register 5 The analog configuration register controls:
- The addition/deletion of the high-pass filter to the ADC signal path
 - The enable/disable of the analog loopback
 - The selection of the regular inputs or auxiliary inputs
 - The function that allows processing of signals that are the sum of the regular inputs and the auxiliary inputs ($V_{IN} + V_{AUX IN}$)
- Register 6 The digital configuration register controls:
- Selection of the free-run function
 - \overline{FSD} [frame-synchronization (sync) delay] output enable/disable
 - Selection of 16-bit function
 - Forcing secondary communications
 - Software reset
 - Software power down
- Register 7 The frame-sync delay register controls the time delay between the master-device frame sync and slave-device frame sync. Register 7 must be the last register programmed when using slave devices since all register data is latched and valid on the sixteenth falling edge of SCLK. On the sixteenth falling edge of SCLK, all delayed frame-sync intervals are shifted by this programmed amount.
- Register 8 The frame-sync number register informs the master device of the number of slaves that are connected in the chain. The frame-sync number is equal to the number of slaves plus one.

2 Detailed Description

2.1 Definitions and Terminology

ADC Channel	All signal processing circuits between the analog input and the digital conversion results at DOUT
Codec Mode	The operating mode under which the device receives shift clock and frame-sync signals from a host processor. The device has no slaves.
d	The d represents valid programmed or default data in the control register format (see Section 2.19, Secondary Serial Communications) when discussing other data-bit portions of the register.
Dxx	Bit position in the primary data word (xx is the bit number)
DAC Channel	All signal processing circuits between the digital data word applied to DIN and the differential output analog signal available at OUT+ and OUT–
Data Transfer Interval	The time during which data is transferred from DOUT and to DIN. This interval is 16 shift clocks regardless of whether the shift clock is internally or externally generated. The data transfer is initiated by the falling edge of the frame-sync signal.
DSxx	Bit position in the secondary data word (xx is the bit number)
FCLK	An internal clock frequency that is a division of MCLK that controls the low-pass filter and (sinx)/x filter clock (see Figure 1–1 and Table 1-1).
f _i	The analog input frequency of interest
Frame Sync	The falling edge of the signal that initiates the data-transfer interval. The primary frame sync starts the primary communications, and the secondary frame sync starts the secondary communications.
Frame Sync and Sampling Period	The time between falling edges of successive primary frame-sync signals
Frame-Sync Interval	The time period occupied by 16 shift clocks. Regardless of the mode of operation, there is always an internal frame-sync interval signal that goes low on the rising edge of SCLK and remains low for 16 shift clocks. It is used for synchronization of the serial-port internal signals. It goes high on the seventeenth rising edge of SCLK.
f _s	The sampling frequency that is the reciprocal of the sampling period.
Host	Any processing system that interfaces to DIN, DOUT, SCLK, or \overline{FS} .
Master Mode	The operating mode under which the device generates and uses its own shift clock and frame-sync signal and generates all delayed frame-sync signals necessary to support slave devices.
Phase Adjustment	The programmed time variation from the falling edge of one frame-sync signal to the falling edge of the next frame sync signal. The time variation is determined by the contents of the A' register. Since the time between falling edges of successive frame-sync signals is the the sampling period, the sampling period is adjusted.
Primary (Serial) Communications	The digital data-transfer interval. Since the device is synchronous, the signal data words from the ADC channel and to the DAC channel occur simultaneously.
Secondary (Serial) Communications	The digital control and configuration data-transfer interval into DIN and the register read-data cycle from DOUT. The data-transfer interval occurs when requested by hardware or software.
Signal Data	The input signal and all of the converted representations through the ADC channel and return through the DAC channel to the analog output. This is contrasted with the purely digital software-control data.
Slave Mode	The operating mode under which the device receives shift clock and frame-sync signals from a master device.

- Stand-Alone Mode The operating mode under which the device generates and uses its own shift clock and frame-sync signal. The device has no slave devices.
- X The X represents a don't-care bit position within the control register format.

2.2 Reset and Power-Down Functions

2.2.1 Reset

The TLC320AC01 resets both the internal counters and registers, including the programmed registers, by any of the following:

- Applying power to the device, causing a power-on reset (POR)
- Applying a low reset pulse to $\overline{\text{RESET}}$
- Reading in the programmable software reset bit (DS01 in register 6)

$\overline{\text{PWR DWN}}$ resets the counters only and preserves the programmed register contents.

2.2.2 Conditions of Reset

The two internal reset signals used for the reset and synchronization functions are as follows:

1. Counter reset: This signal resets all flip-flops and latches that are not externally programmed with the exception of those generating the reset pulse itself. In addition, this signal resets the software power-down bit.

$$\text{Counter reset} = \text{power-on reset} + \overline{\text{RESET}} + \text{RESET bit} + \overline{\text{PWR DWN}}$$

2. Register reset: This signal resets all flip-flops and latches that are not reset by the counter reset except those generating the reset pulse itself.

$$\text{Register reset} = \text{power-on reset} + \overline{\text{RESET}} + \text{RESET bit}$$

Both reset signals are at least one master-clock period long and release on the falling edge of the master clock.

2.2.3 Software and Hardware Power-Down

Given the definitions and conditions of $\overline{\text{RESET}}$, the software-programmed power-down condition is cleared by resetting the software bit (DS00 in register 6) to zero. It is also cleared by either cycling the power to the device, bringing $\overline{\text{PWR DWN}}$ low, or bringing $\overline{\text{RESET}}$ low.

$\overline{\text{PWR DWN}}$ powers down the entire chip (< 1 mA). The software-programmable power-down bit only powers down the analog section of the chip (< 3 mA), which allows a software power-up function. Cycling $\overline{\text{PWR DWN}}$ high to low and back to high resets all flip-flops and latches that are not externally programmed, thereby preserving the register contents.

When $\overline{\text{PWR DWN}}$ is not used, it should be tied high.

2.2.4 Register Default Values After POR, Software Reset, or $\overline{\text{RESET}}$ Is Applied

Register 1 – The A Register

The default value of the A-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

Register 2 – The B Register

The default value of the B-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

Register 3 – The A' Register

The default value of the A'-register data is decimal 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

Register 4 – The Amplifier Gain-Select Register

The default value of the amplifier gain-select register data is shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	1	0	1

Register 5 – The Analog Control Configuration Register

The power-up and reset conditions are as shown below. In the read mode, eight bits are read but the four LSBs are repeated as the four MSBs.

DS03	DS02	DS01	DS00
0	0	0	1

Register 6 – The Digital Configuration Register

The default value of DS07 – DS00 is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

Register 7 – The Frame-Sync Delay Register

The default value of DS07 – DS00 is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

Register 8 – The Frame-Sync Number Register

The default value of DS07 – DS00 is 1 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	1

2.3 Master-Slave Terminal Function

Table 2–1 describes the function of the master/slave (M/\bar{S}) input. The only difference between master and slave operations in the TLC320AC01 is that SCLK and \bar{FS} are outputs when M/\bar{S} is high and inputs when M/\bar{S} is low.

Table 2–1. Master-Slave Selection

MODE	M/\bar{S} †	\bar{FS}	SCLK
Master and Stand Alone	H	Output	Output
Slave and Codec Emulation	L	Input	Input

† When the stand-alone mode is desired or when the device is permanently in the master mode, M/\bar{S} must be high.

2.4 ADC Signal Channel

To produce excellent common-mode rejection of unwanted signals, the analog signal is processed differentially until it is converted to digital data. The signal is amplified by the input amplifier at one of three software selectable gains (typically 0 dB, 6 dB, or 12 dB). A squelch mode can also be programmed for the input amplifier.

The amplifier output is filtered and applied to the ADC input. The ADC converts the signal into discrete digital words in 2s-complement format corresponding to the analog-signal value at the sampling time. These 16-bit digital words, representing sampled values of the analog input signal, are clocked out of the serial port (DOUT), one word for each primary communication interval. During secondary communications, the data previously programmed into the registers can be read out with the appropriate register address and with the read bit set to 1. When a register read is not requested, all 16 bits are 0.

2.5 DAC Signal Channel

DIN receives the 16-bit serial data word (2s complement) from the host during the primary communications interval and latches the data on the seventeenth rising edge of SCLK. The data are converted to an analog voltage by the DAC with a sample and hold and then through a $(\sin x)/x$ correction circuit and a smoothing filter. An output buffer with three software-programmable gains (0 dB, –6 dB, and –12 dB), as shown in register 4, drives the differential outputs OUT+ and OUT–. A squelch mode can also be programmed for the output buffer. During secondary communications, the configuration program data are read into the device control registers.

2.6 Serial Interface

The digital serial interface consists of the shift clock, the frame-synchronization signal, the ADC-channel data output, and the DAC-channel data input. During the primary 16-bit frame-synchronization interval, the SCLK transfers the ADC channel results from DOUT and transfers 16-bit DAC data into DIN.

During the secondary frame-synchronization interval, the SCLK transfers the register read data from DOUT when the read bit is set to a 1. In addition, the SCLK transfers control and device parameter information into DIN. The functional sequence is shown in Figure 2–1.

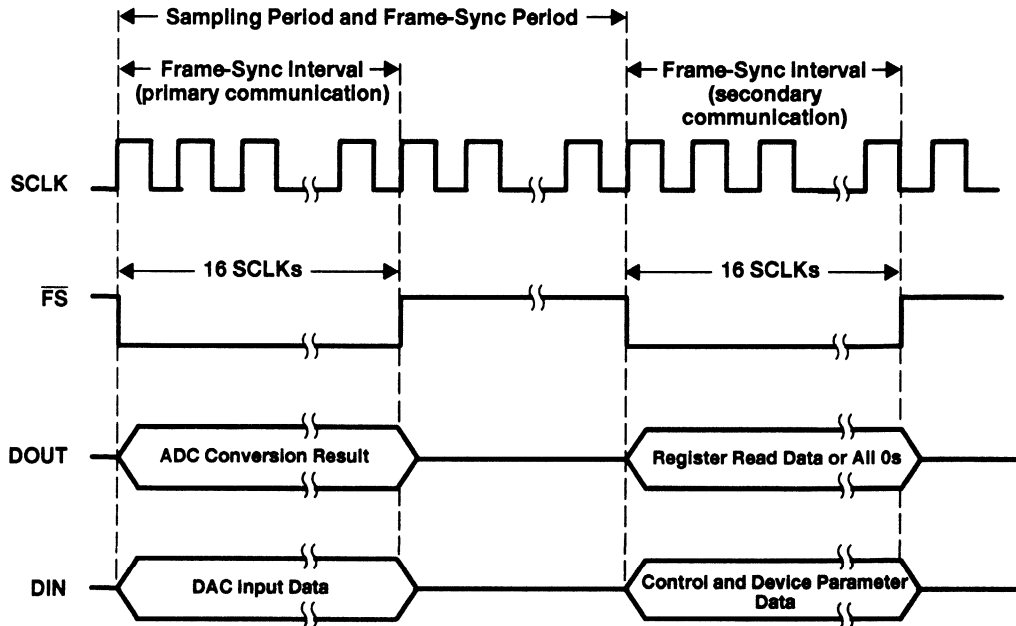


Figure 2–1. Functional Sequence for Primary and Secondary Communication

2.7 Number of Slaves

The number of slaves is determined by the sum of the individual device delays from the frame-sync (\overline{FS}) input low to the frame-sync delayed (FSD) low for all slaves as follows:

$$(n) \times tp(FS-FSD) < 1/2 \text{ shift-clock period}$$

Where:

n is the number of slave devices.

Example:

From the above equation, the number of slaves is given by:

$$(n) \leq \frac{1}{2} \times (\text{SCLK period}) \times \frac{1}{tp(FS - FSD)}$$

assuming the shift clock is 2.4 MHz and $tp(FS - FSD)$ is 40 ns, then the number of slaves is:

$$n \leq \frac{1}{2.4 \text{ MHz}} \times \frac{1}{2} \times \frac{1}{40 \text{ ns}} = \frac{1000}{192} = 5.2$$

The maximum number of slaves under these conditions is five. As the SCLK increases in frequency, the number of slaves that can be used decreases.

2.8 Operating Frequencies

2.8.1 Master and Stand-Alone Operating Frequencies

The sampling (conversion) frequency is derived from the master-clock (MCLK) input by the following equation:

$$f_s = \text{Sampling (conversion) frequency} = \frac{\text{MCLK}}{(\text{A register value}) \times (\text{B register value}) \times 2}$$

The inverse is the time between the falling edges of two successive primary frame-synchronization signals. The input and output data clock (SCLK) is given by:

$$\text{SCLK frequency} = \frac{\text{MCLK frequency}}{4}$$

2.8.2 Slave and Codec Operating Frequencies

The slave and codec conversion and the data frequencies are determined by the externally applied SCLK and $\overline{\text{FS}}$ signals.

2.9 Switched-Capacitor Filter Frequency (FCLK)

The filter clock (FCLK) is an internal clock signal that determines the filter band-pass frequency and is the B counter clock. The frequency of the filter clock is derived by the following equation:

$$\text{FCLK} = \frac{\text{MCLK}}{(\text{A register value}) \times 2}$$

2.10 Filter Bandwidths

The low-pass (LP) filter –3 dB corner is derived by:

$$f(\text{LP}) = \frac{\text{FCLK}}{40} = \frac{\text{MCLK}}{40 \times (\text{A register value}) \times 2}$$

The high-pass (HP) filter –3 dB corner is derived by:

$$f(\text{HP}) = \frac{\text{Sampling frequency}}{200} = \frac{\text{MCLK}}{200 \times 2 \times (\text{A register value}) \times (\text{B register value})}$$

2.11 Required Minimum Number of MCLK Periods

The number of MCLKs necessary for proper operation when only the primary communications are used is:

$$\begin{aligned} \text{Total number of MCLKs} &= (16 + 2) \text{ SCLKs} \times 4 \text{ MCLKs per SCLK} \\ &= 72 \text{ MCLKs minimum} \end{aligned}$$

The number of MCLKs necessary for proper operation if both the primary and secondary communications are used is:

$$\begin{aligned} \text{Total number of MCLKs} &= (16 + 2) \text{ SCLKs} \times 2 \times 4 \text{ MCLKs per SCLK} \\ &= 144 \text{ MCLKs minimum} \end{aligned}$$

Even though the TLC320AC01 can perform with this number of MCLKs, the host may need more time to execute the required software instructions between primary and secondary communication intervals.

2.12 Master and Stand-Alone Modes

The difference between the master and stand-alone modes is that in the stand-alone mode there are no slave devices. Functionally these two modes are the same. In both, the AIC internally generates the shift clock and frame-sync signal for the serial communications. These signals and the filter clock (FCLK) are derived from the input master clock. The master clock applied at the MCLK input determines the internal device timing. The shift clock frequency is a divide-by-four of the master clock frequency and shifts both the

input and output data at DIN and DOUT, respectively, during the frame-sync interval (16 shift clocks long). To begin the communication sequence, the device is reset (see Section 2.2.1, Reset), and the first frame sync occurs approximately 648 master clocks after the reset condition disappears.

2.12.1 Register Programming

All register programming occurs during secondary communications, and data is latched and valid on the sixteenth falling edge of SCLK. After a reset condition, eight primary and secondary communications cycles are required to set up the eight programmable registers. Registers 1 through 8 are programmed in secondary communications intervals 1 through 8, respectively. If the default value for a particular register is desired, that register does not need to be addressed during the secondary communications. The no-op command addresses the pseudo-register (register 0), and no register programming takes place during this communications. The no-op command allows phase shifts of the sampling period without reprogramming any register.

During the eight register programming cycles, DOUT is in the high-impedance state. DOUT is released on the rising edge of the eighth primary internal frame-sync interval. In addition, each register can be read back during DOUT secondary communications by setting the read bit to 1 in the appropriate register. Since the register is in the read mode, no data can be written to the register during this cycle. To return this register to the write mode requires a subsequent secondary communication (see Section 2.19, Secondary Serial Communications for detailed register description).

2.12.2 Master and Stand-Alone Functional Sequence

The A counter counts according to the contents of the A register, and the A counter frequency is divided by two to produce the filter clock (FCLK). The B counter is clocked by FCLK with the following functional sequence:

1. The B counter starts counting down from the B register value minus one. Each count remains in the counter for one FCLK period including the zero count. This total counter time is referred to as the B cycle. The end of the zero count is called the end of B cycle.
2. When the B counter gets to a count of nine, the analog-to-digital (A-to-D) conversion starts.
3. The A-to-D conversion is complete ten FCLK periods later.
4. \overline{FS} goes low on a rising edge of SCLK after the A-to-D conversion is complete. That rising edge of SCLK must be preceded by a falling edge of SCLK, which is the first falling edge to occur after the end of B cycle.
5. The D-to-A conversion cycle begins on the rising edge of the internal frame-sync interval and is complete ten FCLK periods later.

2.13 Slave and Codec Modes

The only difference between the slave and codec modes is that the codec mode is controlled directly by the host and does not use a delayed frame-sync signal. In both modes, the shift clock and the frame sync are both externally generated and must be synchronous with MCLK. The conversion frequency is set by the time interval of externally applied frame-sync falling edges except when the free-run function is selected by bit 5 of register 6 (see Section 2.15.4, Free-Run Mode). The slave device or devices share the shift clock generated by the master device but receive the frame sync from the previous slave in the chain. The Nth slave \overline{FS} receives the (N-1)st slave \overline{FSD} output and so on. The first slave device in the chain receives \overline{FSD} from the master.

2.13.1 Slave and Codec Functional Sequence

The A counter counts according to the contents of the A register, and the A counter frequency is divided by two to produce the FCLK. The device function in the slave or codec mode is the same as steps 1 through 3 of the B cycle description in the master mode but differs as follows:

1. Same as master
2. Same as master
3. Same as master
4. All internal clocks stop 1/2 FCLK before the end of count 0 in the B counter cycle.
5. All internal clocks are restarted on the first rising edge of MCLK after the external \overline{FS} input goes low. This operation provides the synchronization necessary when using an external \overline{FS} signal.
6. The D-to-A conversion starts on the rising edge of the internally generated frame-sync interval at the end of the 16-shift clock data transfer.

In the slave mode, the master controls the phase adjustments for itself and all slaves since all devices are programmed in the same frame-sync interval. In the codec mode, the shift clock and frame sync are externally generated and provide the timing for the ADC and DAC if the free-run function has not been selected (see Section 2.15.4, Free-Run Mode). In the codec mode, there is usually no need for phase adjustments; however, any required phase adjustments must be made by adjusting the external frame-sync timing (sampling time).

2.13.2 Slave Register Programming

When slave devices are used on power-up or reset, all slave frame-sync signals occur at the same time as the master frame-sync signal and all slave devices are programmed during the master secondary frame-sync interval with the same data as the master. The last register programmed must be the frame-sync delay (FSD) register because the delay starts immediately on the rising edge of the seventeenth shift clock of that frame-sync interval. After the FSD register programming is completed for the master and slave, the slave primary frame interval is shifted in time (time slot allocated) according to the data contained in the slave FSD registers. The master then generates frame-sync intervals for itself and each slave to synchronize the host serial port for data transfers for itself and all slave devices.

The number of slaves is specified in the FSN register (register 8); therefore, the number of frame-sync intervals generated by the master is equal to the number of slaves plus one (see Section 2.7, Number of Slaves). These master frame-sync intervals are separated in time by the delay time specified by the FSD register (register 7). These master-generated intervals are the only frame-sync interval signals applied to the host serial port to provide the data-transfer time slot for the slave devices.

2.14 Terminal Functions

2.14.1 Frame-Sync Function

The frame-sync signal indicates that the device is ready to send and receive data for both master and slave modes. The data transfer begins on the falling edge of the frame-sync signal.

2.14.1.1 Frame Sync (\overline{FS}), Master Mode

The frame sync is generated internally. \overline{FS} goes low on the rising edge of SCLK and remains low for the 16-bit data transfer. In addition to generating its own frame-sync interval, the master also outputs a frame sync for each slave that is being used.

2.14.1.2 Frame-Sync Delayed ($\overline{\text{FSD}}$), Master Mode

For the master, the frame-sync delayed output occurs 1/2 shift-clock period ahead of $\overline{\text{FS}}$ to compensate for the time delay through the master and slave devices. The timing relationships are as follows:

1. When the FSD register data is 0, then $\overline{\text{FSD}}$ goes low on the falling edge of SCLK prior to the rising edge of SCLK when $\overline{\text{FS}}$ goes low (see Figure 4–4).
2. When the FSD register data is greater than 16, then $\overline{\text{FSD}}$ goes low on a rising edge of SCLK that is the FSD register number of SCLKs after the falling edge of $\overline{\text{FS}}$.

Register data values from 1 to 16 result in the default register value of zero.

2.14.1.3 Frame Sync ($\overline{\text{FS}}$), Slave Mode

The frame-sync timing is generated externally, applied to $\overline{\text{FS}}$, and controls the ADC and DAC timing (see Section 2.15.4, Free-Run Mode). The external frame-sync width must be a minimum of one shift clock to be recognized and can remain low until the next data frame is required.

2.14.1.4 Frame-Sync Delayed ($\overline{\text{FSD}}$), Slave Mode

This output is fed from the master to the first slave and the first slave $\overline{\text{FSD}}$ output to the second and so on down the chain. The FSD timing sequence in the slave mode is as follows:

1. When the FSD register data is 0, then $\overline{\text{FSD}}$ goes low after $\overline{\text{FS}}$ goes low (see Figure 4–5).
2. When the FSD register data is greater than 16, $\overline{\text{FSD}}$ goes low on a rising edge of SCLK that is the FSD register number of SCLKs after the falling edge of $\overline{\text{FS}}$.

Data values from 1 to 16 are constrained because the data transfer requires 16 clock periods.

2.14.2 Data Out (DOUT)

DOUT is placed in the high-impedance state on the seventeenth rising edge of SCLK (internal or external) after the falling edge of frame sync. In the primary communication, the data word is the ADC conversion result. In the secondary communication, the data is the register read results when requested by the read/write (R/W) bit with the eight MSBs set to 0 (see Section 2.16, Serial Communications). If no register read is requested, the secondary word is all zeroes.

2.14.2.1 Data Out, Master Mode

In the master mode, DOUT is taken from the high-impedance state by the falling edge of frame sync. The most significant data bit then appears on DOUT.

2.14.2.2 Data Out, Slave Mode

In the slave mode, DOUT is taken from the high-impedance state by the falling edge of the external frame sync or the rising edge of the external SCLK, whichever occurs first (see Figure 4–7). The falling edge of frame sync can occur $\pm 1/4$ SCLK period around the SCLK rising edge (see Figure 4–3). The most significant data bit then appears on DOUT.

2.14.3 Data In (DIN)

In the primary communication, the data word is the digital input signal to the DAC channel. In the secondary communication, the data is the control and configuration data to set up the device for a particular function (see Section 2.16, Serial Communications).

2.14.4 Hardware Program Terminals (FC1 and FC0)

These inputs provide for hardware programming requests for secondary communication or phase adjustment. These inputs work in conjunction with the control bits D01 and D00 of the primary data word or control bits DS15 and DS14 of the secondary data word. The data on FC1 and FC0 are latched on the rising edge of the next internally generated primary or secondary frame-sync interval. These inputs should be tied low if not used (see Section 2.17, Request for Secondary Serial Communication and Table 2–3).

2.14.5 Midpoint Voltages (ADC V_{MID} and DAC V_{MID})

Since the device operates at a single-supply voltage, two midpoint voltages are generated for internal signal processing. ADC V_{MID} is used for the ADC channel reference, and DAC V_{MID} is used for the DAC channel reference. Two references minimize channel-to-channel noise and crosstalk. ADC V_{MID} and DAC V_{MID} must be buffered when used as a reference for external signal processing.

2.15 Device Functions

2.15.1 Phase Adjustment

In some applications, such as modems, the device sampling period may require an adjustment to synchronize with the incoming bit stream to improve the signal-to-noise ratio. The TLC320AC01 can adjust the sampling period through the use of the A' register and the control bits.

2.15.1.1 Phase-Adjustment Control

A phase adjustment is a programmed variation in the sampling period. A sampling period is adjusted according to the data value in the A' register, and the phase adjustment is that number of master clocks (MCLK). An adjustment is made during device operation with data bits D01 and D00 in the primary communication, with data bits DS15 and DS14 in the secondary word or in combination with the hardware terminals FC1 and FC0 (see Table 2–3). This adjustment request is latched on the rising edge of the next internal frame-sync interval and is only valid for the next sampling period. To repeat the phase adjustment, another phase request must be initiated.

2.15.1.2 Use of the A' Register for Phase Adjustment

The A' register value makes slight timing adjustments to the sampling period. The sampling period increases or decreases according to the sign of the programmed A' register value and the state of data bits D01 and D00 in the primary data word.

The general equation for the conversion frequency is given as:

$$f_s = \text{conversion frequency} = \frac{\text{MCLK}}{(2 \times \text{A register value} \times \text{B register value}) \pm (\text{A' register value})}$$

Therefore, if A' = 0, the device conversion (sampling) frequency and period is constant.

If a nonzero A' value is programmed, the sampling frequency and period responds as shown in Table 2–2.

Table 2–2. Sampling Variation With A'

D01	D00	SIGN OF THE A' REGISTER VALUE	
		PLUS VALUE (+)	NEGATIVE VALUE (-)
0	1 (increase command)	Frequency decreases, period increases	Frequency increases, period decreases
1	0 (decrease command)	Frequency increases, period decreases	Frequency decreases, period increases

An adjustment to the sampling period, which must be requested through D01 and D00 of the primary data word to DIN, is valid for the following sampling period only. When the adjustment is required for the subsequent sampling period, it must be requested again through D01 and D00 of the primary data word. For each request, only the sampling period occurring immediately after the primary data word request is affected.

The amount of time shift in the entire sampling period ($1/f_s$) is as follows:

When the sampling period is set to 125 μ s (8 kHz), the A' register is loaded with decimal 10 and the TLC320AC01 master clock frequency is 10.386 MHz. The amount of time each sampling period is increased or decreased, when requested, is:

$$\text{Time shift} = (\text{A' register value}) \times (\text{MCLK period})$$

The device changes the entire sampling period by only the MCLK period times the A' register value.

$$\begin{aligned} \text{Change in sampling period} &= \text{contents of A' register} \times \text{master clock period} \\ &= 10 \times 96.45 \text{ ns} = 964 \text{ ns (less than 1\% of the sampling period)} \end{aligned}$$

The sampling period changes by 964.5 ns each time the phase adjustment is requested by the primary data word (i.e., once per sampling period).

It is evident then that the change in sampling period is very small compared to the sampling period. To observe this effect over a long period of time ($>$ sampling period), this change must be continuously requested by the primary data word. If the adjustment is not requested again, the sampling period changes only once and it may appear that there was no execution of the command. This is especially true when bench testing the device. Automatic test equipment can test for results within a single sampling period.

Internally, the A' register value only affects one cycle (period) of the A counter. The A and A' values are additive, but only for one A-counter period. The A counter begins the first count at the default or programmed A-register value and counts down to the A'-register value. As the A' value increases or decreases, the first clock cycle from the A counter is lengthened or shortened. The initial A-counter period is the only counter period affected by the A' register such that only this single period is increased or decreased.

2.15.2 Analog Loopback

This function allows the circuit to be tested remotely. In loopback, OUT+ and OUT- are internally connected to IN+ and IN-. The DAC data bits D15 to D02 that are applied to DIN can be compared with the ADC output data bits D15 to D02 at DOUT. There are some differences due to the ADC and DAC channel offset. The loopback function is implemented by setting DS01 and DS00 to zero in control register 5 (see Section 2.19, Secondary Serial Communications).

2.15.3 16-Bit Mode

In the 16-bit mode, the device ignores the last two control bits (D01 and D00) of the primary word and requests continual secondary communications to occur. By ignoring the last two primary communication bits, compatibility with existing 16-bit software can be maintained. This function is implemented by setting bit DS03 to 1 in register 6. To return to normal operation, DS03 must be reprogrammed to 0.

2.15.4 Free-Run Mode

With the free-run bit set in register 6, the external shift clock and frame sync control only the data transfer. The ADC and DAC timing are controlled by the A and B register values, and the phase-shift adjustment must be done as if the device is in stand-alone mode (by the software or the state of FC1 and FC0).

Phase adjustment cannot be made by adjustment of the frame-sync timing. The external frame sync must occur within 1/2 FCLK period of the internal frame sync (FCLK as determined by the values of the A and B registers).

When the external frame sync occurs simultaneously with the internal load, the data-transfer request by the external frame sync takes precedence over an internal load command. The latching of the ADC conversion data in the output register is inhibited until the current 16 bits are shifted out of the register by the shift clock.

2.15.5 Force Secondary Communication

With bit 2 in register 6 set to 1, secondary communication is requested continuously. It overrides all software and hardware requests concerning secondary communication. Phase shifting, however, can still be performed with the software and hardware.

2.15.6 Enable Analog Input Summing

By setting bits DS01 and DS00 to 11 in register 5, the normal analog input voltage is summed with the auxiliary input voltage. The gain for the analog input amplifier is set by data bits DS03 and DS02 in register 4.

2.15.7 DAC Channel (sin x)/x Error Correction

The (sin x)/x compensation filter is designed for zero (sin x)/x error using a B-register value of 15. Since the filter cannot be removed from the signal path, operation using another B-register value results in an error in the reconstructed analog output. The error is given by the following equation. Any error compensation needed by a given application can be performed in the software.

$$\text{DAC channel frequency response error} = 20 \times \log_{10} \left[\frac{\sin \left(\frac{2\pi \times A \times B}{f_{\text{MCLK}}} \times f \right)}{\sin \left(\frac{30\pi \times A}{f_{\text{MCLK}}} \times f \right)} \times \frac{15}{B} \right]$$

where:

- f = the frequency of interest
- f_{MCLK} = the TLC320AC01 master-clock frequency
- A = the A-register value
- B = the B-register value

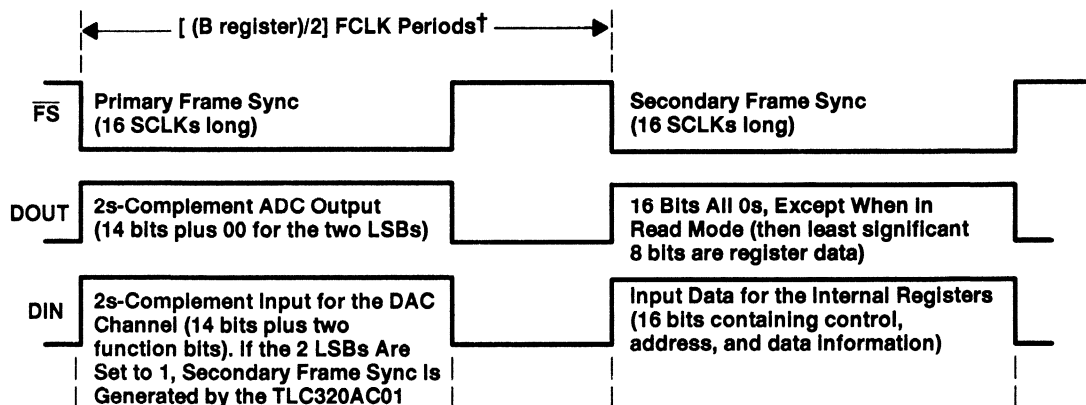
and the arguments of the sin functions are in radians.

2.16 Serial Communications

2.16.1 Stand-Alone and Master-Mode Word Sequence and Information Content During Primary and Secondary Communications

For the stand-alone and master modes, the sequence in Figure 2–2 shows the relationship between the primary and secondary communications interval, the data content into DIN, and the data content from DOUT.

The TLC320AC01 can provide a phase-shift command or the next secondary communications interval by decoding 1) the programmed state of the FC1 and FC0 inputs and the D01 and D00 data bits in the primary data word, or 2) the state of the FC1 and FC0 inputs and the DS15 and DS14 data bits in the secondary data word (see Table 2–3). When DS13 (the R/W bit) is the default value of 0, all 16 bits from DOUT are 0 during secondary communication. However, when the R/W bit is set to 1 in the secondary communication control word, the secondary transmission from DOUT still contains 0s in the eight MSBs. The lower order eight bits contain the data of the register currently being addressed. This function provides register status information for the host.

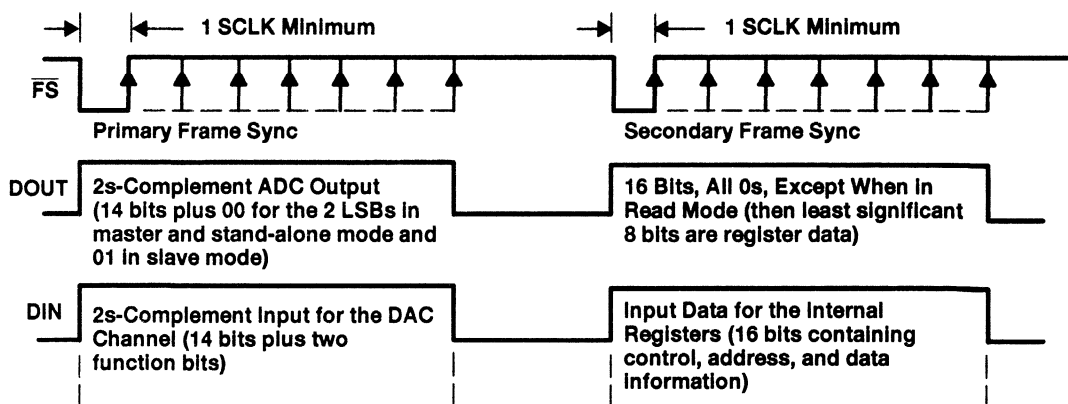


† The time between the primary and secondary frame sync is the time equal to filter clock (FCLK) period multiplied by the B-register contents divided by two. The time interval is rounded to the nearest shift clock. The secondary frame-sync signal goes from high to low on the next shift clock low-to-high transition after (B register/2) filter clock periods.

Figure 2–2. Master and Stand-Alone Functional Sequence

2.16.2 Slave- and Codec-Mode Word Sequence and Information Content During Primary and Secondary Communications

For the slave and codec modes, the sequence is basically the same as the stand-alone and master modes with the exception that the frame sync and the shift clock are generated and controlled externally as shown in Figure 2–3. For the codec mode, the frame-sync pulse width needs to be a minimum of one shift clock long. The timing relationship between the frame sync and shift clock is shown in the timing diagrams. Phase shifting is usually not required in the slave or codec mode because the frame-sync timing can be adjusted externally if required.



NOTE: The time between the primary and secondary frame syncs is determined by the application; however, enough time must be provided so that the host can execute the required number of software instructions in the time between the end of the primary data transfer (rising edge of the primary frame-sync interval) and the falling edge of the secondary frame sync (start of secondary communications).

Figure 2–3. Slave and Codec Functional Sequence

2.17 Request for Secondary Serial Communication and Phase Shift

The following paragraphs describe a request for secondary serial communication and phase shift using hardware control inputs FC1 and FC0, primary data bits D01 and D00, and secondary data bits DS15 and DS14.

2.17.1 Initiating a Request

Combinations of FC1 and FC0 input conditions, bits D01 and D00 in the primary serial data word, FC1 and FC0, and bits DS15 and DS14 in the secondary serial data word can initiate a secondary serial communication or request a phase shift according to the following rules (see Table 2–3).

1. Primary word phase shifts can be requested by either the hardware or software when the other set of signals are 11 or 00. If both hardware and software request phase shifts, the software request is performed.
2. Secondary words can be requested by either the software or hardware at the same time that the other set of signals is requesting a phase shift.
3. Hardware inputs FC1 and FC0 are ignored during the secondary word unless DS15 and DS14 are 11. When DS15 and DS14 are 01 or 10, the corresponding phase shift is performed. When DS15 and DS14 are 00, no phase shift is performed even when the hardware requests a phase shift.

2.17.2 Normal Combinations of Control

The normal combinations of control are as follows:

1. Use D01 and D00 and DS15 and DS14 to request phase shifts and secondary words by holding FC1 and FC0 to 00.
2. Use FC1 and FC0 exclusively to request phase shifts and secondary words by holding D01 and D00 to 00 and DS15 and DS14 to 11.
3. Use D01 and D00 only to request secondary words and FC1 and FC0 to perform phase shifts once per period by holding DS15 and DS14 to 00.

2.17.3 Additional Control Options

Additional control options are unusual and are rarely needed or used; however, they are as follows:

1. Use D01 and D00 only to request secondary words and FC1 and FC0 to perform phase shifts twice per period by holding DS15 and DS14 to 11.
2. Use FC1 and FC0 exclusively to request secondary words and D01 and D00 and DS15 and DS14 to perform phase shifts twice per period.
3. Use FC1 and FC0 to perform the phase shift after the primary word and DS15 and DS14 to perform a phase shift after the secondary word by holding D01 and D00 to 11.

**Table 2–3. Software and Hardware Requests for
Secondary Serial-Communication and Phase-Shift Truth Table**

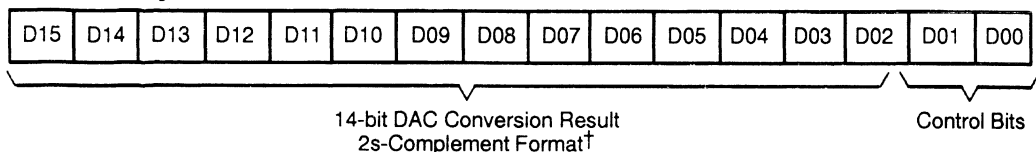
WITHIN PRIMARY OR SECONDARY DATA WORD	CONTROL BITS		HARDWARE TERMINALS		PHASE-SHIFT ADJUSTMENT (see Section 2.15.1)		SECONDARY REQUEST (see Note 1)
	D01	D00	FC1	FC0	EARLIER	LATER	
Primary	0	0	0	0	0	0	0
	0	0	0	1	0	1	0
	0	0	1	0	1	0	0
	0	0	1	1	0	0	1
	0	1	0	0	0	1	0
	0	1	0	1	0	1	0
	0	1	1	0	0	1	0
	0	1	1	1	0	1	1
	1	0	0	0	1	0	0
	1	0	0	1	1	0	0
	1	0	1	0	1	0	0
	1	0	1	1	1	0	1
	1	1	0	0	0	0	1
	1	1	0	1	0	1	1
	1	1	1	0	1	0	1
	1	1	1	1	0	0	1
Secondary	DS15	DS14	FC1	FC0	EARLIER	LATER	No request can be made for secondary communication within the secondary word.
	0	0	0	0	0	0	
	0	0	0	1	0	0	
	0	0	1	0	0	0	
	0	0	1	1	0	0	
	0	1	0	0	0	1	
	0	1	0	1	0	1	
	0	1	1	0	0	1	
	0	1	1	1	0	1	
	1	0	0	0	1	0	
	1	0	0	1	1	0	
	1	0	1	0	1	0	
	1	0	1	1	1	0	
	1	1	0	0	0	0	
	1	1	0	1	0	1	
	1	1	1	0	1	0	
1	1	1	1	0	0		

NOTE 1: The 0 state indicates that a secondary communication is not being requested. The 1 state indicates that a secondary communication is being requested.

2.18 Primary Serial Communications

Primary serial communications transfer the 14-bit DAC input plus two control bits (D01 and D00) to DIN of the TLC320AC01. They simultaneously transfer the 14-bit ADC conversion result from DOUT to the processor. The two LSBs are set to 0 in the ADC result.

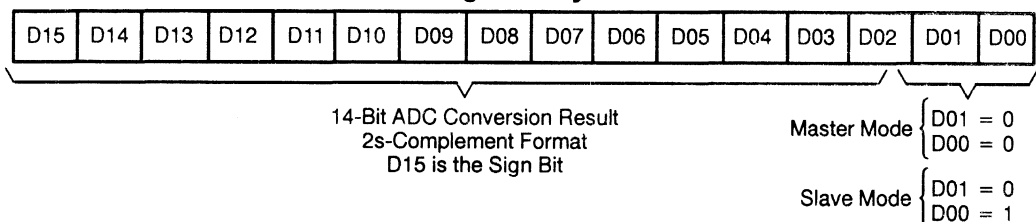
2.18.1 Primary Serial Communications Data Format



† Since the supply voltage is single ended, the reference for 2s-complement format is ADC V_{MID} . Voltages above this reference have a 0 as the MSB, and voltages below this reference have a 1 as the MSB.

During primary serial communications, when D01 and D00 are both high in the DAC data word to DIN, a subsequent 16 bits of control information is received by the device at DIN during a secondary serial-communication interval. This secondary serial-communication interval begins at 1/2 the programmed conversion time when the B register data value is even or 1/2 the programmed value minus one FCLK when the B register data value is odd. The time between primary and secondary serial communication is measured from the falling edge of the primary frame sync to the falling edge of the secondary frame sync (see Section 2.19, Secondary Serial Communications for function and format of control words).

2.18.2 Data Format From DOUT During Primary Serial Communications



2.19 Secondary Serial Communications

2.19.1 Data Format to DIN During Secondary Serial Communications

There are nine 16-bit configuration and control registers numbered from zero to eight. All register data contents are represented in 2s-complement format. The general format of the commands during secondary serial communications is as follows.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits (2 bits)		R/W Bit	Register Address (5 bits)					Register Data Value (8 bits)							

All control register words are latched in the register and valid on the sixteenth falling edge of SCLK.

2.19.2 Control Data-Bit Function in Secondary Serial Communication

2.19.2.1 DS15 and DS14

In the secondary data word, bits DS15 and DS14 perform the same control function as the primary control bits D01 and D00 do in the primary data word.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/W	Register Address					Register Data							

Hardware terminals FC1 and FC0 are valid inputs when DS15 and DS14 are both high, and they are ignored for all other conditions.

2.19.2.2 DS13 (R/W Bit)

Reset and power-up procedures set this bit to a 0, placing the device in the write mode. When this bit is set to 1, however, the previous data content of the register being addressed is read out to the host from DOUT as the least significant eight bits of the 16-bit secondary word. The first eight bits remain set to 0. Reading the data out is nondestructive, and the contents of the register remain unchanged.

A. Write Mode (DS13 = 0)

Data In. The data word to DIN has the following general format in the write mode.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	0	Register Address						Register Data							

Data Out. The shift clock shifts out all 0s as the pattern to the host from DOUT.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

B. Read Mode (DS13 = 1)

Data In. The data word to DIN has the following format to allow a register read. Phase shifts can also be done in the read mode.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	1	Register Address						Ignored							

Data Out. The shift clock clocks out the data of the register addressed from DOUT in the read mode in the eight LSBs.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0	Register Data							

2.20 Internal Register Format

2.20.1 Pseudo-Register 0 (No-Op Address)

This address represents a no-operation command. No register I/O operation takes place, so the device can receive secondary commands for phase adjustment without reprogramming any register. A read of the no-op is 0. The format of the command word is as follows.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	X	0	0	0	0	0	0	X	X	X	X	X	X	X	X

2.20.2 Register 1 (A Register)

The following command loads DS07 (MSB) – DS00 into the A register.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	R/W	0	0	0	0	1	Register Data								

The data in DS07 – DS00 determines the division of the master clock to produce the internal FCLK.

$$\text{FCLK frequency} = \text{MCLK}/(\text{A register contents} \times 2)$$

The default value of the A-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

2.20.3 Register 2 (B Register)

The following command loads DS07 (MSB) – DS00 into the B register.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/ \bar{W}	0	0	0	1	0	Register Data							

The data in DS07 – DS00 controls the division of FCLK to generate the conversion clock.

$$\begin{aligned} \text{Conversion frequency} &= \text{FCLK}/(\text{B register contents}) \\ &= \frac{\text{MCLK}}{2 \times \text{A register contents} \times \text{B register contents}} \end{aligned}$$

The default value of the B-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

2.20.4 Register 3 (A' Register)

The following command contains the A'-register address and loads DS07(MSB) – DS00 into the A' register.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/ \bar{W}	0	0	0	1	1	Register Data							

The data in DS07 – DS00 is in 2s-complement format and controls the number of master-clock periods that the sampling time is shifted.

The default value of the A'-register data is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

2.20.5 Register 4 (Amplifier Gain-Select Register)

The following command contains the amplifier gain-select register address with selection code for the monitor output (DS05–DS04), analog input (DS03–DS02), and analog output (DS01–DS00) programmable gains.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	R/W	0	0	1	0	0	X	X	*	*	*	*	*	*	*
Monitor output gain = squelch										0	0				
Monitor output gain = 0 dB										0	1				
Monitor output gain = -8 dB										1	0				
Monitor output gain = -18 dB										1	1				
Analog input gain = squelch												0	0		
Analog input gain = 0 dB												0	1		
Analog input gain = 6 dB												1	0		
Analog input gain = 12 dB												1	1		
Analog output gain = squelch														0	0
Analog output gain = 0 dB														0	1
Analog output gain = -6 dB														1	0
Analog output gain = -12 dB														1	1

The default value of the monitor output gain is squelch, which corresponds to data bits DS05 and DS04 equal to 00 (binary).

The default value of the analog input gain is 0 dB, which corresponds to data bits DS03 and DS02 equal to 01 (binary).

The default value of the analog output gain is 0 dB, which corresponds to data bits DS01 and DS00 equal to 01 (binary).

The default data value is shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	1	0	1

2.20.6 Register 5 (Analog Configuration Register)

The following command loads the analog configuration register with the individual bit functions described below.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	R/W	0	0	1	0	1	X	X	X	X	*	*	*	*	
Must be set to 0												0			
High-pass filter disabled													1		
High-pass filter enabled													0		
Analog loopback enabled														0	0
Enables IN+ and IN- (disables AUXIN+ and AUXIN-)														0	1
Enables AUXIN+ and AUXIN- (disables IN+ and IN-)														1	0
Enable analog input summing														1	1

The default value of the high-pass-filter enable bit is 0, which places the high-pass filter in the signal path. The default values of DS01 and DS00 are 0 and 1 which enables IN+ and IN-.

The power-up and reset conditions are as shown below.

DS03	DS02	DS01	DS00
0	0	0	1

In the read mode, eight bits are read but the four LSBs are repeated as the four MSBs.

2.20.7 Register 6 (Digital Configuration Register)

The following command loads the digital configuration register with the individual bit functions described below.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/ \bar{W}	0	0	1	1	0	X	X	*	*	*	*	*	*
ADC and DAC conversion free run										1					
Inactive										0					
FSD output disable										1					
Enable										0					
16-Bit mode, ignore primary LSBs											1				
Normal operation											0				
Force secondary communications												1			
Normal operation												0			
Software reset													1		
(upon reset, this bit is automatically reset to 0)															
Inactive reset													0		
Software power-down active (automatically reset to 0															1
after PWR DWN is cycled high to low and back to high)															
Power-down function external															0
(uses PWR DWN)															

The default value of DS07–DS00 is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

2.20.8 Register 7 (Frame-Sync Delay Register)

The following command contains the frame-sync delay (FSD) register address and loads DS07 (MSB)–DS00 into the FSD register. The data byte (DS01–DS00) determines the number of SCLKs between \bar{FS} and the delayed frame-sync signal, \bar{FSD} . The minimum data value for this register is decimal 18.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/ \bar{W}	0	0	1	1	1	Register Data							

The default value of DS07 – DS00 is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

When using a slave device, register 7 must be the last register programmed.

2.20.9 Register 8 (Frame-Sync Number Register)

The following command contains the frame-sync number (FSN) register address and loads DS07 (MSB)–DS00 into the FSN register. The data byte determines the number of frame-sync signals generated by the TLC320AC01. This number is equal to the number of slaves plus one.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/W	0	1	0	0	0	Register Data							

The default value of DS07–DS00 is 1 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	1

3 Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (Unless Otherwise Noted)†

Supply voltage range, DGTL V_{DD} (see Notes 1 and 2)	–0.3 V to 6.5 V
Supply voltage range, DAC V_{DD} (see Notes 1 and 2)	–0.3 V to 6.5 V
Supply voltage range, ADC V_{DD} (see Notes 1 and 2)	–0.3 V to 6.5 V
Differential supply voltage range, DGTL V_{DD} to DAC V_{DD}	–0.3 V to 6.5 V
Differential supply voltage range, all positive supply voltages to ADC GND, DAC GND, DGTL GND, SUBS	–0.3 V to 6.5 V
Output voltage range, DOUT	–0.3 V to DGTL V_{DD} + 0.3 V
Input voltage range, DIN	–0.3 V to DGTL V_{DD} + 0.3 V
Ground voltage range, ADC GND, DAC GND, DGTL GND, SUBS	–0.3 V to DGTL V_{DD} + 0.3 V
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	–40°C to 125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

3.2 Recommended Operating Conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{DD}	Positive supply voltage	4.5	5	5.5	V
	Steady-state differential voltage between any two supplies			0.1	V
V_{IH}	High-level digital input voltage	2.2			V
V_{IL}	Low-level digital input voltage			0.8	V
I_O	Load output current from ADC V_{MID} and DAC			100	μ A
	Conversion time for the ADC and DAC channels		10 FCLK periods		
f_{MCLK}	Master-clock frequency		10.368	15	MHz
$V_{ID(PP)}$	Analog input voltage (differential, peak to peak)		6		V
R_L	Differential output load resistance	600			Ω
	Single-ended to buffered DAC V_{MID} voltage load resistance	300			
T_A	Operating free-air temperature	0		70	°C

- NOTES: 1. Voltage values for DGTL V_{DD} are with respect to DGTL GND, voltage values for DAC V_{DD} are with respect to DAC GND, and voltage values for ADC V_{DD} are with respect to ADC GND. For the subsequent electrical, operating, and timing specifications, the symbol V_{DD} denotes all positive supplies. DAC GND, ADC GND, DGTL GND, and SUBS are at 0 V unless otherwise specified.
2. To avoid possible damage to these CMOS devices and associated operating parameters, the sequence below should be followed when applying power:
- (1) Connect SUBS, DGTL GND, ADC GND, and DAC GND to ground.
 - (2) Connect voltages ADC V_{DD} , and DAC V_{DD} .
 - (3) Connect voltage DGTL V_{DD} .
 - (4) Connect the input signals.

When removing power, follow the steps above in reverse order.

3.3 Electrical Characteristics Over Recommended Range of Operating Free-Air Temperature, MCLK = 5.184 MHz, V_{DD} = 5 V, Outputs Unloaded, Total Device

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
I _{DD}	Supply current	PWR $\overline{\text{DWN}}$ = 1 and clock signals present		20	25	mA
		PWR $\overline{\text{DWN}}$ = 0 after 500 μ s and clock signals present		1	2	mA
P _D	Power dissipation	PWR $\overline{\text{DWN}}$ = 1 and clock signals present		100		mW
		PWR $\overline{\text{DWN}}$ = 0 after 500 μ s and clock signals present		5		mW
		Software power down, (bit D00, register 6 set to 1)		15	20	mW
ADC V _{MID}	Midpoint voltage	No load	ADC V _{DD} /2 - 0.1		ADC V _{DD} /2 + 0.1	V
DAC V _{MID}	Midpoint voltage	No load	DAC V _{DD} /2 - 0.1		DAC V _{DD} /2 + 0.1	V

3.4 Electrical Characteristics Over Recommended Range of Operating Free-Air Temperature, V_{DD} = 5 V, Digital I/O Terminals (DIN, DOUT, EOC, FC0, FC1, $\overline{\text{FS}}$, $\overline{\text{FSD}}$, MCLK, M $\overline{\text{S}}$, SCLK)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH}	High-level output voltage	I _{OH} = -1.6 mA	2.4			V
V _{OL}	Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
I _{IH}	High-level input current, any digital input	V _I = 2.2 V to DGTL V _{DD}			10	μ A
I _{IL}	Low-level input current, any digital input	V _I = 0 V to 0.8 V			10	μ A
C _i	Input capacitance				5	pF
C _o	Output capacitance				5	pF

† All typical values are at V_{DD} = 5 V and T_A = 25°C.

3.5 Electrical Characteristics Over Recommended Range of Operating Free-Air Temperature, V_{DD} = 5 V, ADC and DAC Channels

3.5.1 ADC Channel Filter Transfer Function, FCLK = 144 kHz, f_s = 8 kHz

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Gain relative to gain at f _i = 1020 Hz (see Note 3)	f _i = 50 Hz		-2	dB
	f _i = 200 Hz	-1.8	-0.15	
	f _i = 300 Hz to 3 kHz	-0.15	0.15	
	f _i = 3.3 kHz	-0.35	0.03	
	f _i = 3.4 kHz	-1	-0.1	
	f _i = 4 kHz		-14	
	f _i \geq 4.6 kHz		-32	

NOTE 3: The differential analog input signals are sine waves at 6 V peak to peak. The reference gain is at 1020 Hz.

3.5.2 ADC Channel Input, $V_{DD} = 5\text{ V}$, Input Amplifier Gain = 0 dB (Unless Otherwise Noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{I(PP)}$	Peak-to-peak input voltage (see Note 4)	Single-ended		3		V
		Differential		6		V
	ADC converter offset error	Band-pass filter selected	10	30		mV
CMRR	Common-mode rejection ratio at IN+, IN-, AUX IN+, AUX IN- (see Note 5)			55		dB
r_i	Input resistance at IN+, IN-, AUX IN+, AUX IN-			100		k Ω
	Squelch	DS03, DS02 = 0 in register 4		60		dB

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 4. The differential range corresponds to the full-scale digital output.

5. Common-mode rejection ratio is the ratio of the ADC converter offset error with no signal and the ADC converter offset error with a common-mode nonzero signal applied to either IN+ and IN- together or AUX IN+ and AUX IN- together.

3.5.3 ADC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = 6\text{ dB}$		$A_V = 12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
ADC channel signal-to-distortion ratio (see Note 6)	$V_I = -6\text{ dB to } -1\text{ dB}$	68		—		—		dB
	$V_I = -12\text{ dB to } -6\text{ dB}$	63		68		—		
	$V_I = -18\text{ dB to } -12\text{ dB}$	56		63		68		
	$V_I = -24\text{ dB to } -18\text{ dB}$	51		57		63		
	$V_I = -30\text{ dB to } -24\text{ dB}$	43		51		57		
	$V_I = -36\text{ dB to } -30\text{ dB}$	39		45		51		
	$V_I = -42\text{ dB to } -36\text{ dB}$	33		39		45		
	$V_I = -48\text{ dB to } -42\text{ dB}$	27		32		39		

NOTE 6: The analog-input test signal is a 1020-Hz sine wave with 0 dB = 6 V peak to peak as the reference level for the analog-input signal.

3.5.4 DAC Channel Filter Transfer Function, $F_{CLK} = 144\text{ kHz}$, $f_s = 9.6\text{ kHz}$, $V_{DD} = 5\text{ V}$

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Gain relative to gain at $f_i = 1020\text{ Hz}$ (see Note 7)	$f_i < 200\text{ Hz}$		0.15	dB
	$f_i = 200\text{ Hz}$	-0.5	0.15	
	$f_i = 300\text{ Hz to } 3\text{ kHz}$	-0.15	0.15	
	$f_i = 3.3\text{ kHz}$	-0.35	0.03	
	$f_i = 3.4\text{ kHz}$	-1	-0.1	
	$f_i = 4\text{ kHz}$		-14	
	$f_i \geq 4.6\text{ kHz}$		-32	

NOTE 7: The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak.

3.5.5 DAC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = -6\text{ dB}$		$A_V = -12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
DAC channel signal-to-distortion ratio (see Note 8)	$V_O = -6\text{ dB to }0\text{ dB}$	68	—	—	—	—	—	dB
	$V_O = -12\text{ dB to }-6\text{ dB}$	63	—	68	—	—	—	
	$V_O = -18\text{ dB to }-12\text{ dB}$	57	—	63	—	68	—	
	$V_O = -24\text{ dB to }-18\text{ dB}$	51	—	57	—	63	—	
	$V_O = -30\text{ dB to }-24\text{ dB}$	45	—	51	—	57	—	
	$V_O = -36\text{ dB to }-30\text{ dB}$	39	—	45	—	51	—	
	$V_O = -42\text{ dB to }-36\text{ dB}$	33	—	39	—	48	—	
$V_O = -48\text{ dB to }-42\text{ dB}$	27	—	33	—	39	—		

NOTE 8: The input signal, V_I , is the digital equivalent of a 1020-Hz sine wave (full-scale analog output at full-scale digital input = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT+ to OUT-.

3.5.6 System Distortion, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$, $F_{CLK} = 144\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC channel attenuation	Second harmonic	Single-ended input (see Note 9)	—	82	—	dB
		Differential input (see Note 9)	70	82	—	
	Third harmonic and higher harmonics	Single-ended input (see Note 9)	—	77	—	
		Differential input (see Note 9)	70	77	—	
DAC channel attenuation	Second harmonic	Single-ended output (buffered DAC V_{MID}) (see Note 10)	—	82	—	
		Differential output (see Note 10)	70	82	—	
	Third harmonic and higher harmonics	Single-ended output (see Note 10)	—	77	—	
		Differential output (see Note 10)	70	77	—	

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

- NOTES: 9. The input signal is a 1020-Hz sine wave for the ADC channel. Harmonic distortion is defined for an input level of -1 dB.
10. The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT+ to OUT-. Harmonic distortion is specified for a signal input level of 0 dB.

3.5.7 Noise, Low-Pass and Band-Pass Switched-Capacitor Filters Included, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC idle-channel noise		Inputs tied to ADC V_{MID} , $f_S = 8\text{ kHz}$, $F_{CLK} = 144\text{ kHz}$, (see Note 11)		180	300	μV_{rms}
DAC idle-channel noise	Broad-band noise	DIN INPUT = 0000000000000000, $f_S = 8\text{ kHz}$, $F_{CLK} = 144\text{ kHz}$, (see Note 12)		180	300	
	Noise (0 to 7.2 kHz)			180	300	
	Noise (0 to 3.6 kHz)			180	300	

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 11. The ADC channel noise is calculated by taking the RMS value of the digital output codes of the ADC channel and converting to microvolts.

12. The DAC channel noise is measured differentially from $OUT+$ to $OUT-$ across $600\ \Omega$.

3.5.8 Absolute Gain Error, $V_{DD} = 5\text{ V}$, $f_S = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
ADC channel absolute gain error (see Note 13)	-1-dB input signal	$T_A = 25^\circ\text{C}$		± 0.5	dB
		$T_A = 0 - 70^\circ\text{C}$		± 1	
DAC channel absolute gain error (see Note 14)	0-dB input signal, $R_L = 600\ \Omega$	$T_A = 25^\circ\text{C}$		± 0.5	
		$T_A = 0 - 70^\circ\text{C}$		± 1	

NOTES: 13. ADC absolute gain error is the variation in gain from the ideal gain over the specified input signal levels. The gain is measured with a -1-dB, 1020-Hz sine wave. The -1-dB input signal allows for any positive gain or offset error that may affect gain measurements at or close to 0-dB input signal levels.

14. The DAC input signal is the digital equivalent of a 1020-Hz sine wave (full-scale analog output at digital full-scale input = 0 dB). The nominal differential DAC channel output voltage with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is $600\ \Omega$ from $OUT+$ to $OUT-$.

3.5.9 Relative Gain and Dynamic Range, $V_{DD} = 5\text{ V}$, $f_S = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
ADC channel relative gain tracking error (see Note 15)	-48-dB to -1-dB input signal range		± 0.15	dB
DAC channel relative gain tracking error (see Note 16)	-48-dB to 0-dB input signal range $R_L(\text{diff}) = 600\ \Omega$		± 0.15	

NOTES: 15. ADC gain tracking is the ratio of the measured gain at one ADC channel input level to the gain measured at any other input level. The ADC channel input is a -1-dB 1020-Hz sine wave input signal. A -1-dB input signal allows for any positive gain or offset error that may affect gain measurements at or close to 0-dB ADC input signal levels.

16. DAC gain tracking is the ratio of the measured gain at one DAC channel digital input level to the gain measured at any other input level. The DAC-channel input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output voltage with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is $600\ \Omega$ from $OUT+$ to $OUT-$.

3.5.10 Power-Supply Rejection, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 17)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC V_{DD}	Supply-voltage rejection ratio, ADC channel	$f_i = 0$ to 30 kHz		50		dB
		$f_i = 30$ to 50 kHz		55		
DAC V_{DD}	Supply-voltage rejection ratio, DAC channel	$f_i = 0$ to 30 kHz		40		
		$f_i = 30$ to 50 kHz		45		
DGTL V_{DD}	Supply-voltage rejection ratio, ADC channel	$f_i = 0$ to 30 kHz		50		
		$f_i = 30$ to 50 kHz		55		
DGTL V_{DD}	Supply-voltage rejection ratio, DAC channel	Single ended, $f_i = 0$ to 30 kHz		40		
		$f_i = 30$ to 50 kHz		45		
		Differential, $f_i = 0$ to 30 kHz		40		
		$f_i = 30$ to 50 kHz		45		

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTE 17: Power supply rejection measurements are made with both the ADC and the DAC channels idle and a 200-mV peak-to-peak signal applied to the appropriate supply.

3.5.11 Crosstalk Attenuation, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC channel crosstalk attenuation	DAC channel idle with DIN = 00000000000000, ADC input = 0 dB, 1020-Hz sine wave, Gain = 0 dB (see Note 18)		80		dB
DAC channel crosstalk attenuation	ADC channel idle with INP, INM, AUX IN+, and AUX IN- at ADC V_{MID}		80		dB
	DAC channel input = digital equivalent of a 1020-Hz sine wave (see Note 19)		80		

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 18. The test signal is a 1020-Hz sine wave with a 0 dB = 6-V peak-to-peak reference level for the analog input signal.

19. The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT+ to OUT-.

3.5.12 Monitor Output Characteristics, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 20)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{O(PP)}$	Peak-to-peak ac output voltage Quiescent level = ADC V_{MID} $Z_L = 10\text{ k}\Omega$ and 60 pF	1.3	1.5		V
V_{OO}	Output offset voltage No load, single ended relative to ADC V_{MID}		5	10	mV
V_{OC}	Output common-mode voltage No load	0.4 ADC V_{DD}	0.5 ADC V_{DD}	0.6 ADC V_{DD}	V
r_o	DC output resistance		50		Ω
A_V	Gain = 0 dB	-0.2	0	0.2	dB
	Gain 2 = -8 dB	-8.2	-8	-7.8	
	Gain 3 = -18 dB	-18.4	-18	-17.6	
	Squelch (see Note 22)			-60	

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 20. All monitor output tests are performed with a $10\text{-k}\Omega$ load resistance.

21. Monitor gains are measured with a 1020-Hz , 6-V peak-to-peak sine wave applied differentially between $IN+$ and $IN-$. The monitor output gains are nominally 0 dB , -8 dB , and -18 dB relative to its input; however, the output gains are -6 dB relative to $IN+$ and $IN-$ or $AUX\ IN+$ and $AUX\ IN-$.

22. Squelch is measured differentially with respect to ADC V_{MID} .

3.6 Timing Requirements and Specifications in Master Mode

3.6.1 Recommended Input Timing Requirements for Master Mode, $V_{DD} = 5\text{ V}$

		MIN	NOM	MAX	UNIT
$t_r(\text{MCLK})$	Master clock rise time		5		ns
$t_f(\text{MCLK})$	Master clock fall time		5		ns
	Master clock duty cycle	40%		60%	
$t_w(\text{RESET})$	$\overline{\text{RESET}}$ pulse duration	1 MCLK			
$t_{su}(\text{DIN})$	DIN setup time before SCLK low (see Figure 4–2)	25			ns
$t_h(\text{DIN})$	DIN hold time after SCLK low (see Figure 4–2)			20	ns

3.6.2 Operating Characteristics Over Recommended Range of Operating Free-Air Temperature, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 23)

PARAMETER		MIN	TYP†	MAX	UNIT
$t_f(\text{SCLK})$	Shift clock fall time (see Figure 4–2)		13	18	ns
$t_r(\text{SCLK})$	Shift clock rise time (see Figure 4–2)		13	18	ns
	Shift clock duty cycle	45%		55%	
$t_d(\text{CH-FL})$	Delay time from SCLK high to $\overline{\text{FSD}}$ low (see Figures 4–2 and 4–4 and Note 24)		5	20	ns
$t_d(\text{CH-FH})$	Delay time from SCLK high to $\overline{\text{FS}}$ high (see Figure 4–2)		5	20	ns
$t_d(\text{CH-DOUT})$	Delay time from SCLK high to DOUT valid (see Figures 4–2 and 4–7)			20	ns
$t_d(\text{CH-DOUTZ})$	Delay time from SCLK \uparrow to DOUT in high-impedance state (see Figure 4–8)		20		ns
$t_d(\text{ML-EL})$	Delay time from MCLK low to EOC low (see Figure 4–9)		40		ns
$t_d(\text{ML-EH})$	Delay time from MCLK low to EOC high (see Figure 4–9)		40		ns
$t_f(\text{EL})$	EOC fall time (see Figure 4–9)		13		ns
$t_r(\text{EH})$	EOC rise time (see Figure 4–9)		13		ns
$t_d(\text{MH-CH})$	Delay time from MCLK high to SCLK high			50	ns
$t_d(\text{MH-CL})$	Delay time from MCLK high to SCLK low			50	ns

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 23. All timing specifications are valid with $C_L = 20\text{ pF}$.

24. $\overline{\text{FSD}}$ occurs 1/2 shift-clock cycle ahead of $\overline{\text{FS}}$ when the device is operating in the master mode.

3.7 Timing Requirements and Specifications in Slave Mode and Codec Emulation Mode

3.7.1 Recommended Input Timing Requirements for Slave Mode, $V_{DD} = 5\text{ V}$

		MIN	NOM	MAX	UNIT
$t_{r(\text{MCLK})}$	Master clock rise time		5		ns
$t_{f(\text{MCLK})}$	Master clock fall time		5		ns
	Master clock duty cycle	40%		60%	
$t_w(\text{RESET})$	$\overline{\text{RESET}}$ pulse duration	1 MCLK			
$t_{su}(\text{DIN})$	DIN setup time before SCLK low (see Figure 4–3)	20			ns
$t_h(\text{DIN})$	DIN hold time after SCLK high (see Figure 4–3)			20	ns
$t_{su}(\text{FL-CH})$	Setup time from $\overline{\text{FS}}$ low to SCLK high			$\pm \text{SCLK}/4$	ns

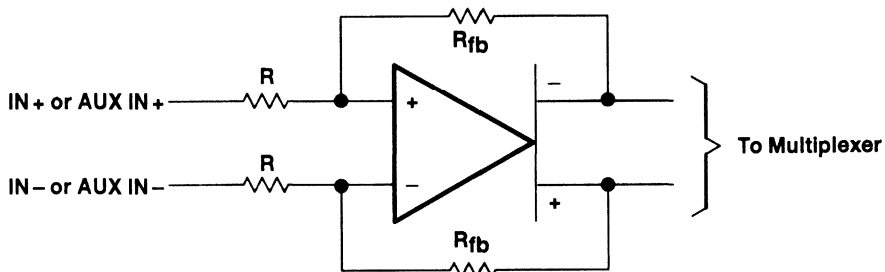
3.7.2 Operating Characteristics Over Recommended Range of Operating Free-Air Temperature, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 23)

PARAMETER		MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$	Shift clock cycle time (see Figure 4–3)	125			ns
$t_f(\text{SCLK})$	Shift clock fall time (see Figure 4–3)			18	ns
$t_r(\text{SCLK})$	Shift clock rise time (see Figure 4–3)			18	ns
	Shift clock duty cycle	45%		55%	
$t_d(\text{CH-FDL})$	Delay time from SCLK high to $\overline{\text{FSD}}$ low (see Figure 4–6)			50	ns
$t_d(\text{CH-FDH})$	Delay time from SCLK high to $\overline{\text{FSD}}$ high			40	ns
$t_d(\text{FL-FDL})$	Delay time from $\overline{\text{FS}}$ low to $\overline{\text{FSD}}$ low (slave to slave) (see Figure 4–5)			40	ns
$t_d(\text{CH-DOUT})$	Delay time from SCLK high to DOUT valid (see Figures 4–3 and 4–7)			40	ns
$t_d(\text{CH-DOUTZ})$	Delay time from SCLK \uparrow to DOUT in high-impedance state (see Figure 4–8)		20		ns
$t_d(\text{ML-EL})$	Delay time from MCLK low to EOC low (see Figure 4–9)		40		ns
$t_d(\text{ML-EH})$	Delay time from MCLK low to EOC high (see Figure 4–9)		40		ns
$t_f(\text{EL})$	EOC fall time (see Figure 4–9)		13		ns
$t_r(\text{EH})$	EOC rise time (see Figure 4–9)		13		ns
$t_d(\text{MH-CH})$	Delay time from MCLK high to SCLK high			50	ns
$t_d(\text{MH-CL})$	Delay time from MCLK high to SCLK low			50	ns

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTE 23: All timing specifications are valid with $C_L = 20\text{ pF}$.

4 Parameter Measurement Information



$R_{fb} = R$ for DS03 = 0 and DS02 = 1
 $R_{fb} = 2R$ for DS03 = 1 and DS02 = 0
 $R_{fb} = 4R$ for DS03 = 1 and DS02 = 1
 $R = 100 \text{ k}\Omega$ nominal

Figure 4-1. IN+ and IN- Gain-Control Circuitry

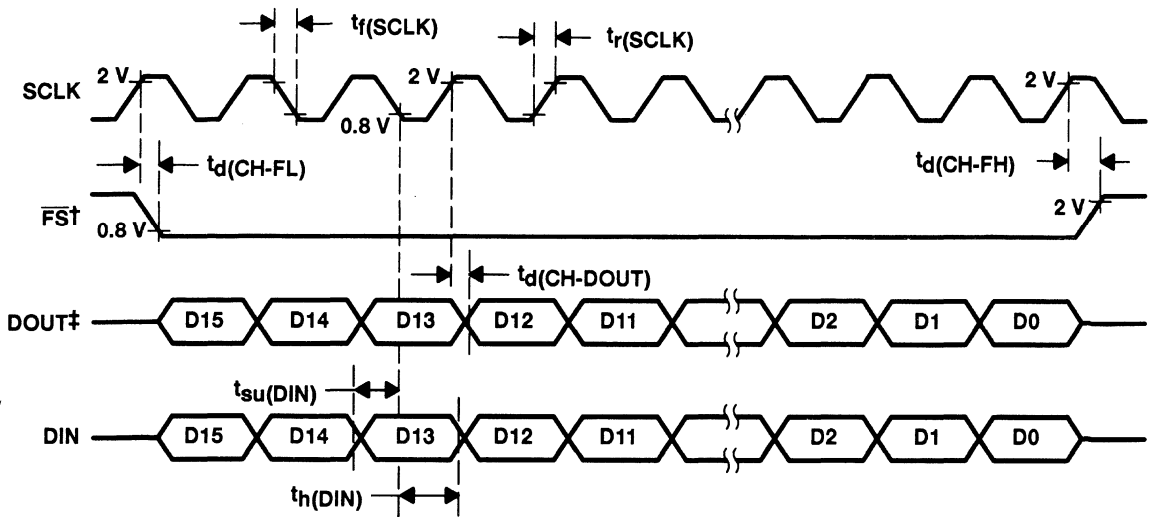
Table 4-1. Gain Control (Analog Input Signal Required for Full-Scale Bipolar A/D-Conversion 2s Complement)[†]

INPUT CONFIGURATION	CONTROL REGISTER 4		ANALOG INPUT [‡]	A/D CONVERSION RESULT
	DS03	DS02		
Differential configuration Analog input = IN+ - IN- = AUX IN+ - AUX IN-	0	0	All	Squelch
	0	1	$V_{ID} = \pm 3 \text{ V}$	\pm Full scale
	1	0	$V_{ID} = \pm 1.5 \text{ V}$	\pm Full scale
	1	1	$V_{ID} = \pm 0.75 \text{ V}$	\pm Full scale
Single-ended configuration [§] Analog input = IN+ - V_{MID} = AUX IN+ - V_{MID}	0	0	All	Squelch
	0	1	$V_I = \pm 1.5 \text{ V}$	\pm Half scale
	1	0	$V_I = \pm 1.5 \text{ V}$	\pm Full scale
	1	1	$V_I = \pm 0.75 \text{ V}$	\pm Full scale

[†] $V_{DD} = 5 \text{ V}$

[‡] V_{ID} = differential input voltage, V_I = input voltage referenced to ADC V_{MID} with IN- or AUX IN- connected to ADC V_{MID} . In order to minimize distortion, it is recommended that the analog input not exceed 0.1 dB below full scale.

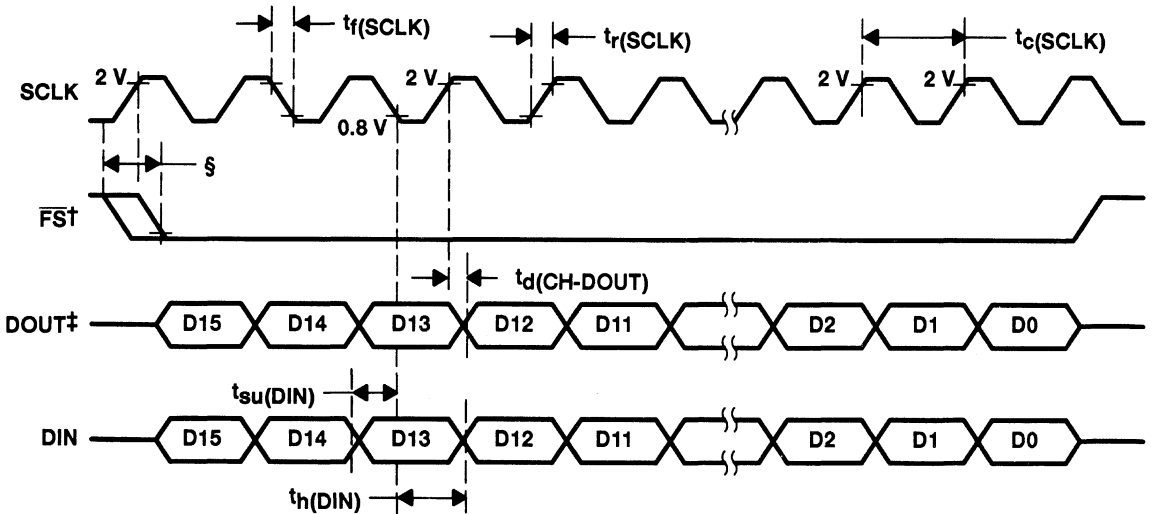
[§] For single-ended inputs, the analog input voltage should not exceed the supply rails. All single-ended inputs should be referenced to the internal reference voltage, ADC V_{MID} , for best common-mode performance.



† The time between falling edges of two primary \overline{FS} signals is the conversion period.

‡ The data on DOUT are shifted out on the rising edge of the shift clock, and the data on DIN are shifted in on the falling edge of the shift clock.

Figure 4–2. AIC Stand-Alone and Master-Mode Timing

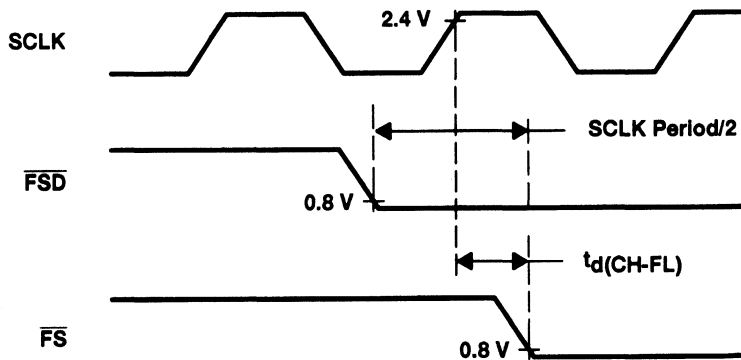


† The time between falling edges of two primary \overline{FS} signals is the conversion period.

‡ The data on DOUT are shifted out on the rising edge of the shift clock, and the data on DIN are shifted in on the falling edge of the shift clock.

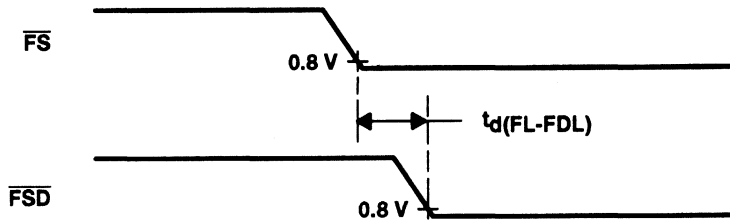
§ The high-to-low transition of \overline{FS} must occur within $\pm 1/4$ of a shift-clock period around the 2-V level of the shift clock.

Figure 4–3. AIC Slave and Codec Emulation Mode



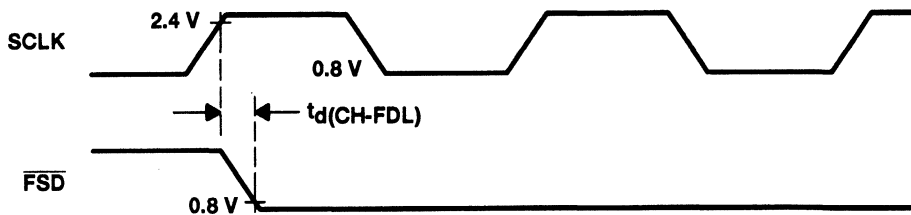
NOTE: Timing shown is for the TLC320AC01 operating as the master or as a stand-alone device.

Figure 4-4. Master or Stand-Alone $\overline{\text{FS}}$ and $\overline{\text{FSD}}$ Timing



NOTE: Timing shown is for the TLC320AC01 operating in the slave mode ($\overline{\text{FS}}$ and SCLK signals are generated externally). The programmed data value in the FSD register is 0.

Figure 4-5. Slave $\overline{\text{FS}}$ to $\overline{\text{FSD}}$ Timing



NOTE: Timing shown is for the TLC320AC01 operating in the slave mode ($\overline{\text{FS}}$ and SCLK signals are generated externally). There is a data value in the FSD register greater than 18 decimal.

Figure 4 - 6. Slave SCLK to $\overline{\text{FSD}}$ Timing

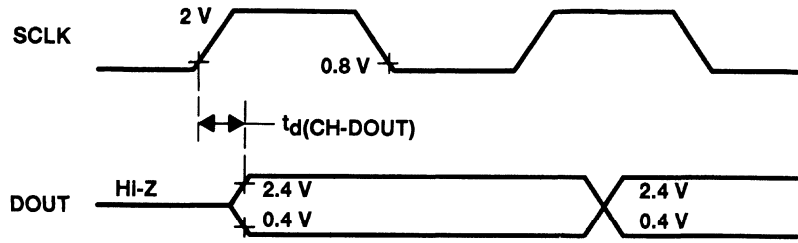


Figure 4–7. DOUT Enable Timing From HI-Z

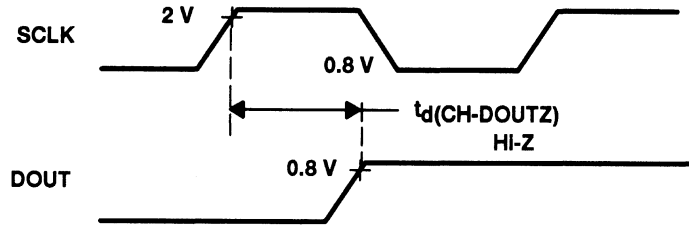


Figure 4–8. DOUT Delay Timing to HI-Z

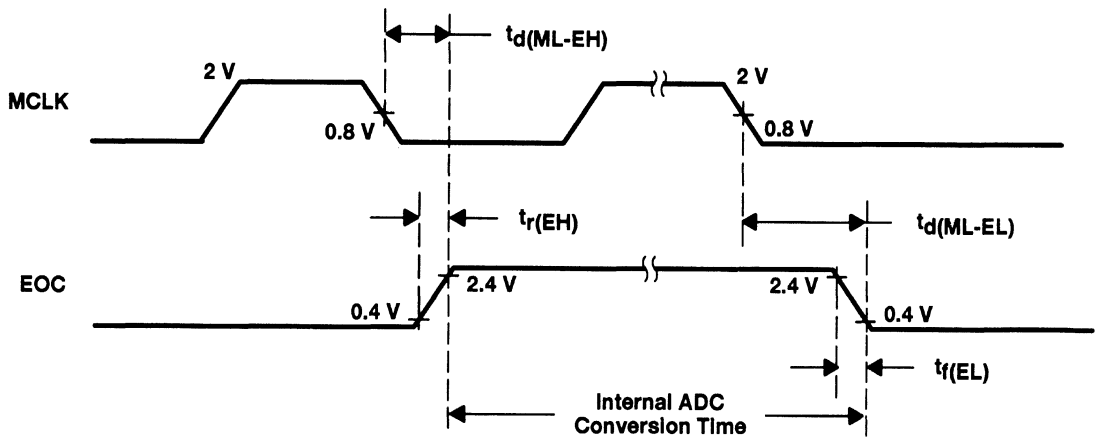
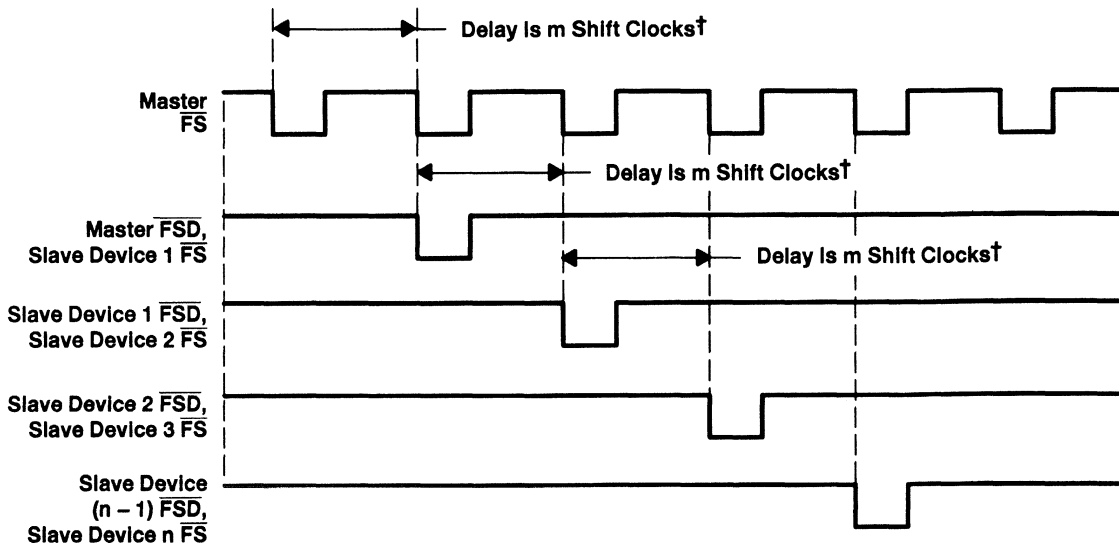


Figure 4–9. EOC Frame Timing



† The delay time from any \overline{FS} signals to the corresponding \overline{FSD} signals is m shift clocks with the value of m being the numerical value of the data programmed into the FSD register. In the master mode with slaves, the same data word programs the master and all slave devices; therefore, master to slave 1, slave 1 to slave 2, slave 2 to slave 3, etc., have the same delay time.

Figure 4–10. Master-Slave Frame-Sync Timing After a Delay Has Been Programmed Into the FSD Registers

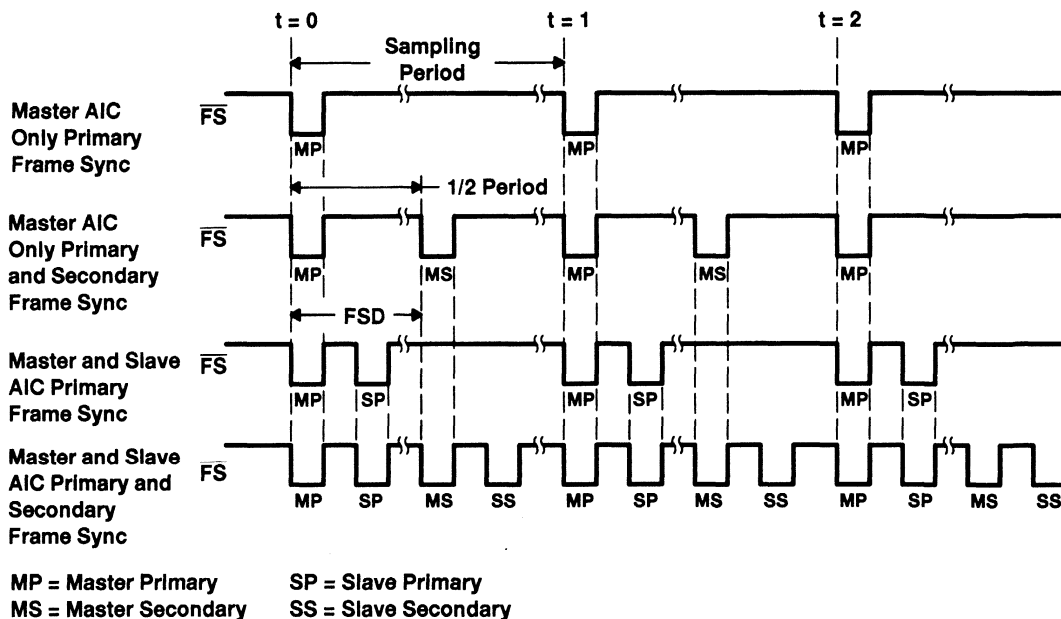


Figure 4–11. Master and Slave Frame-Sync Sequence with One Slave

5 Typical Characteristics

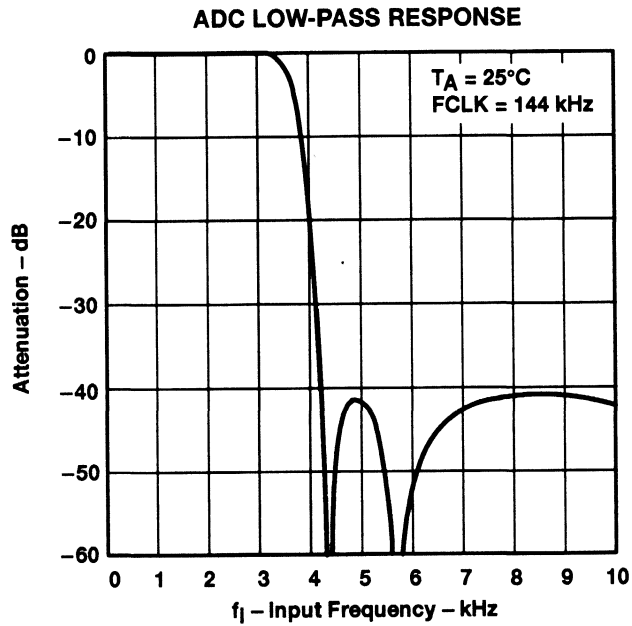


Figure 5-1

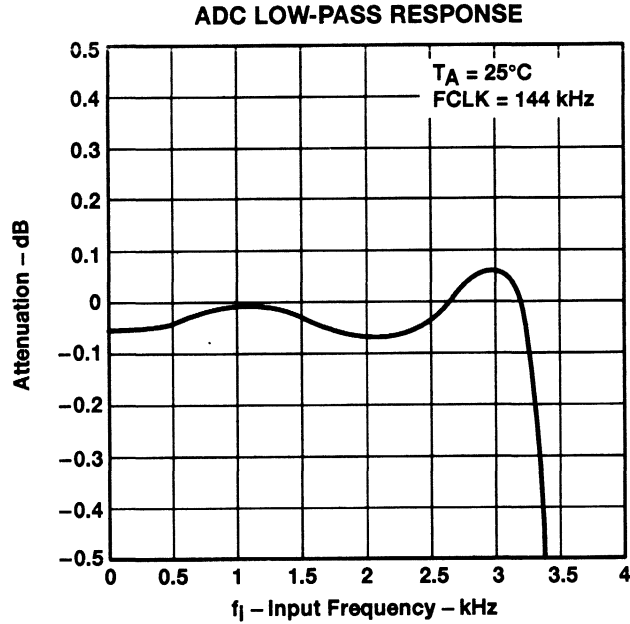


Figure 5-2

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{144}$

ADC GROUP DELAY

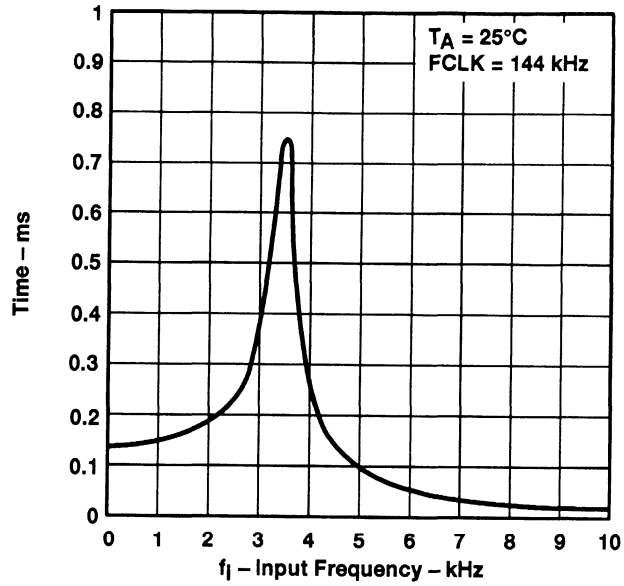


Figure 5-3

ADC BAND-PASS RESPONSE

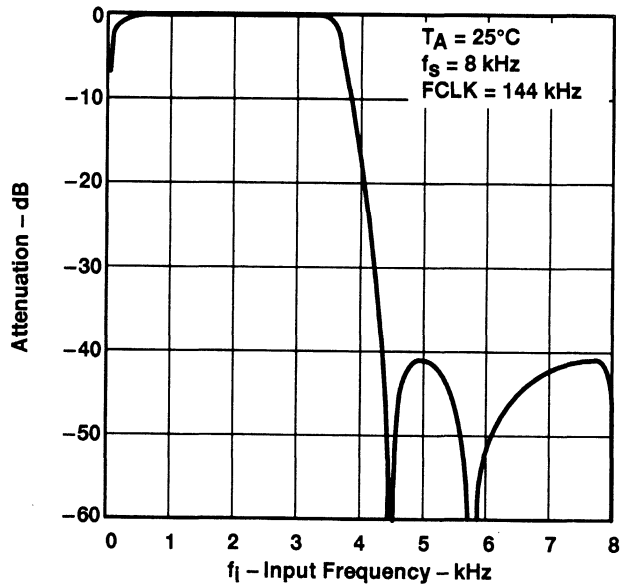


Figure 5-4

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{144}$

ADC BAND-PASS RESPONSE

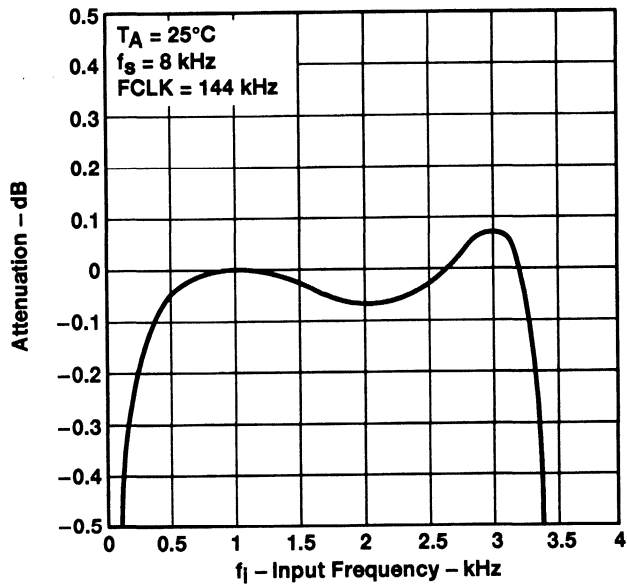


Figure 5-5

ADC HIGH-PASS RESPONSE

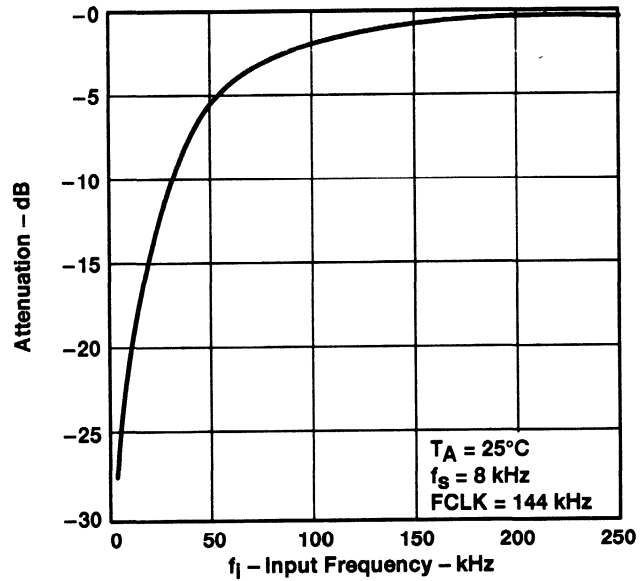


Figure 5-6

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{144}$

ADC BAND-PASS GROUP DELAY

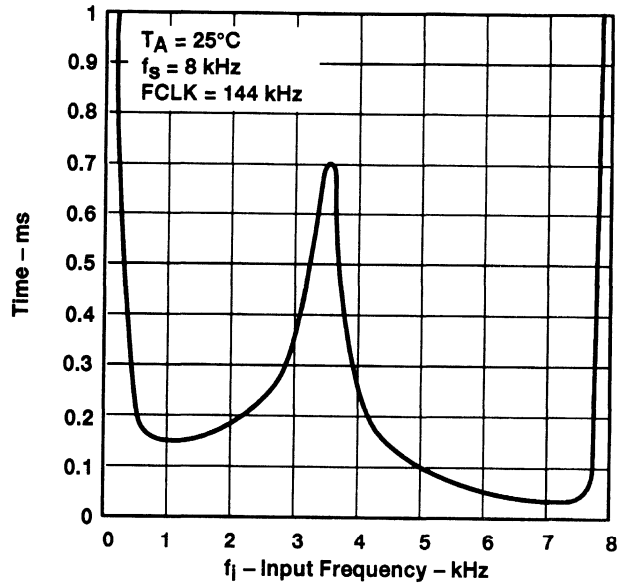


Figure 5-7

DAC LOW-PASS RESPONSE

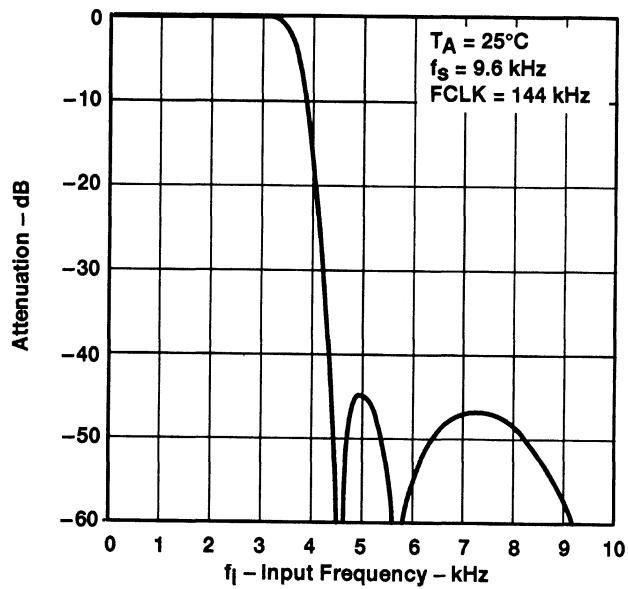


Figure 5-8

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times FCLK \text{ (kHz)}}{144}$

DAC LOW-PASS RESPONSE

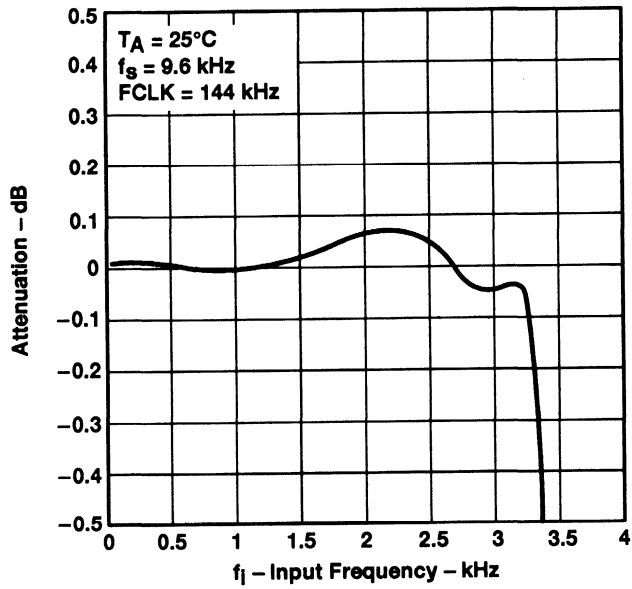


Figure 5-9

DAC LOW-PASS GROUP DELAY

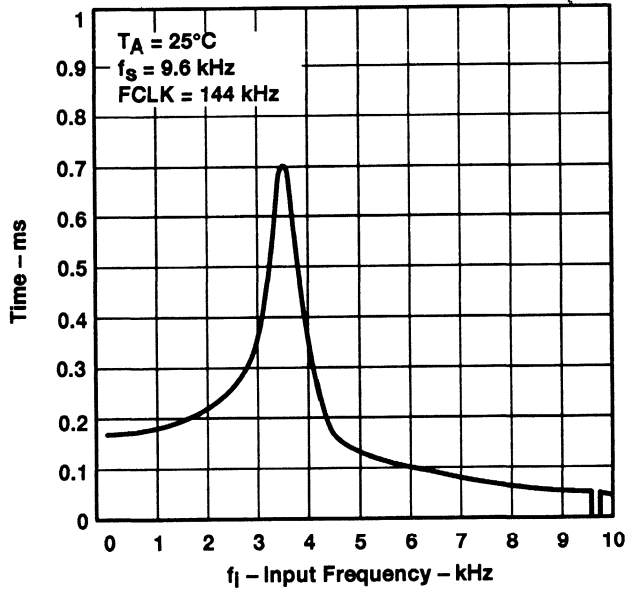


Figure 5-10

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{144}$

DAC (sin x)/x CORRECTION FILTER RESPONSE

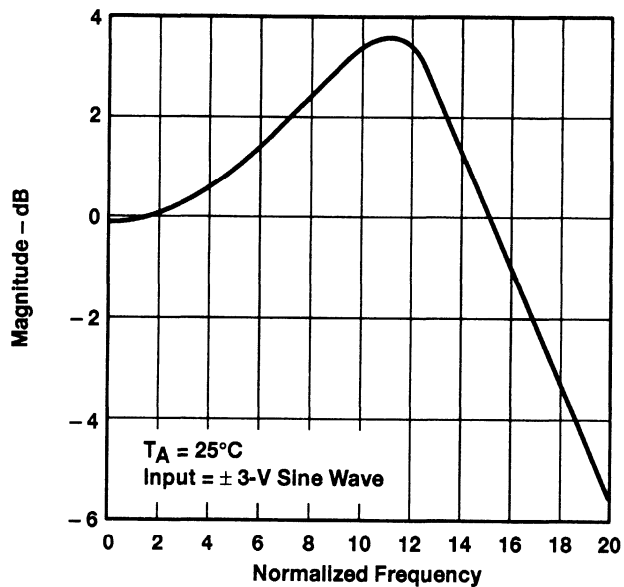


Figure 5-11

DAC (sin x)/x CORRECTION FILTER RESPONSE

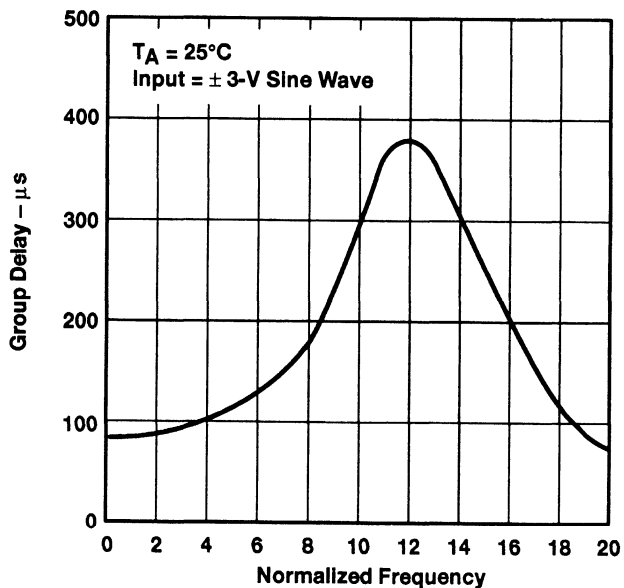


Figure 5-12

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{288}$

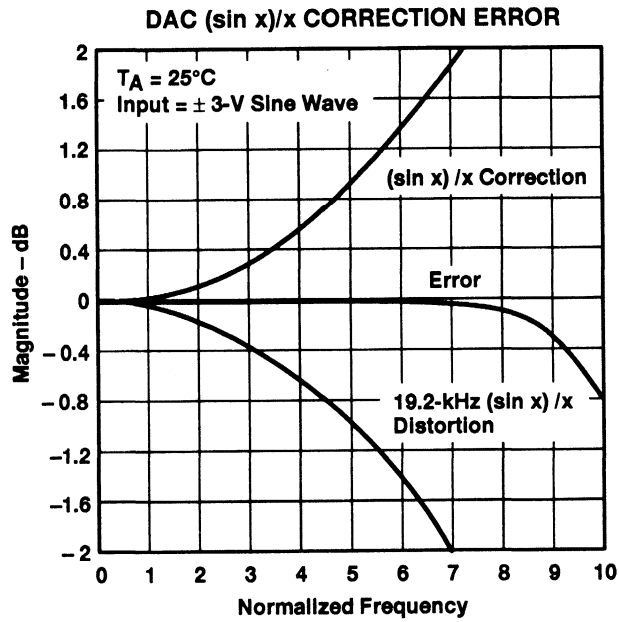


Figure 5-13

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{288}$

6 Application Information

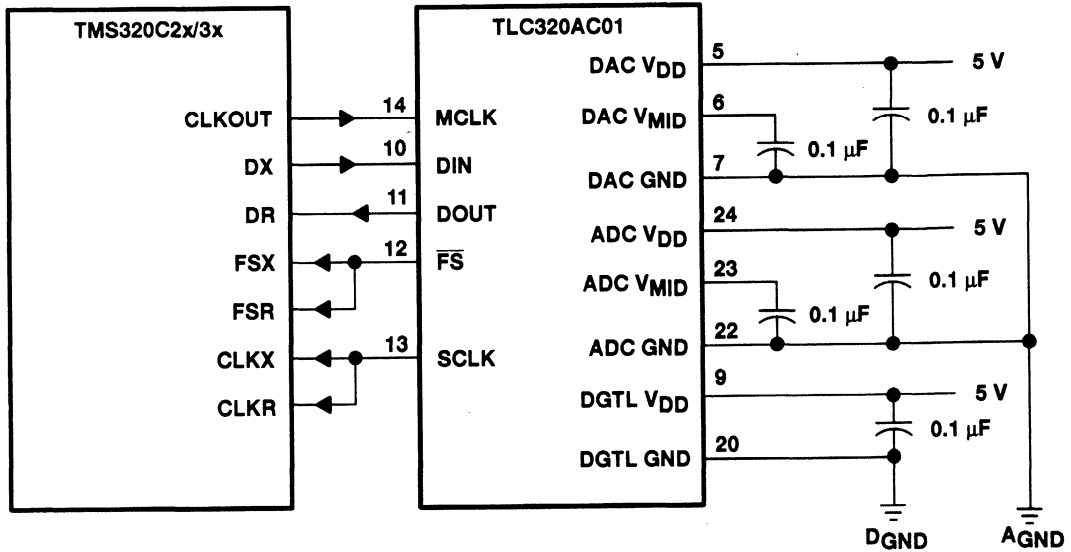


Figure 6-1. Stand-Alone Mode (to DSP Interface)

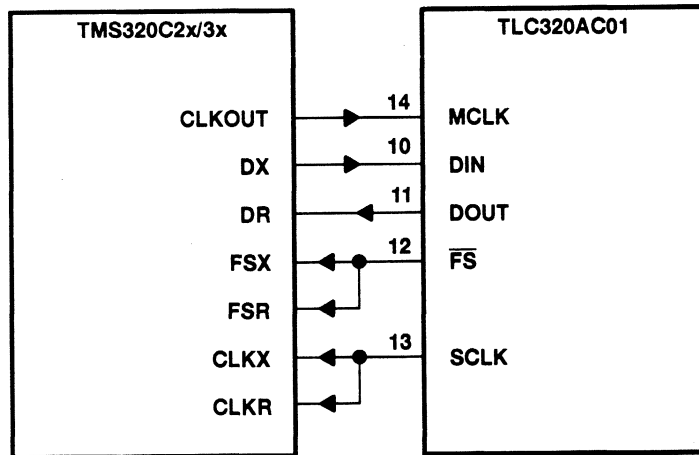
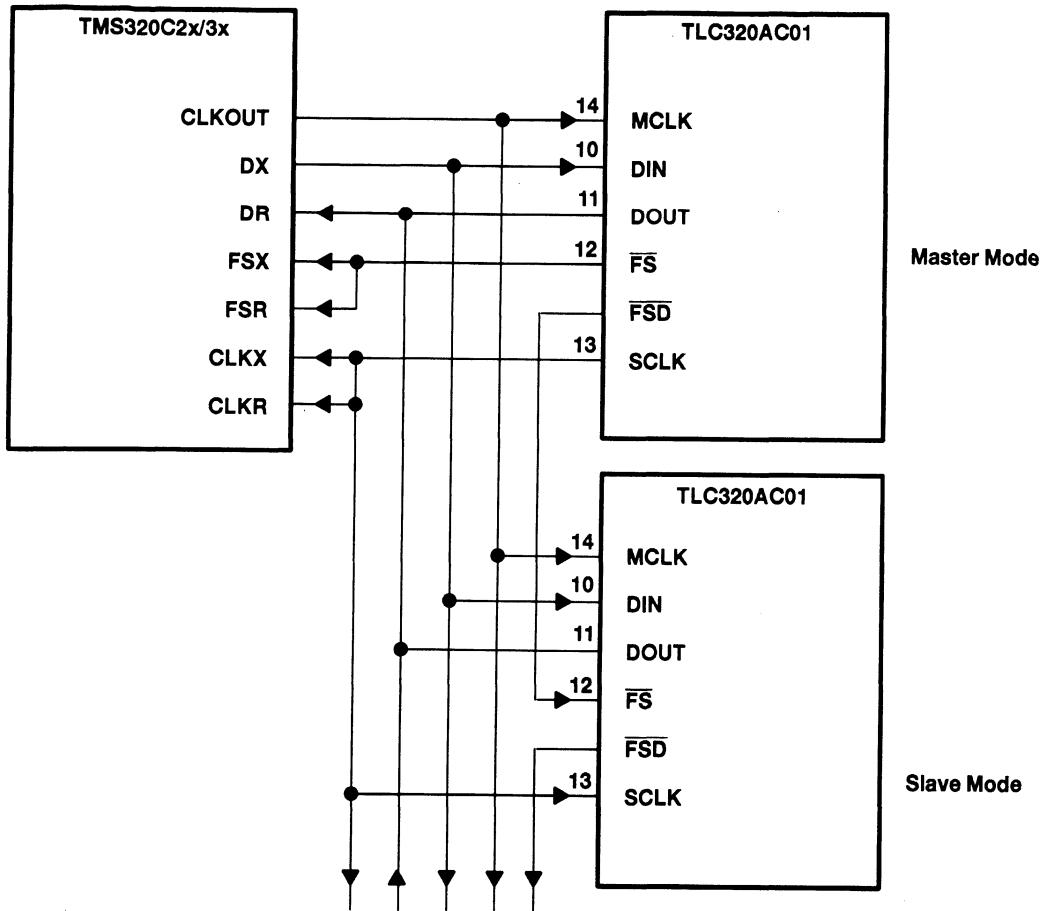


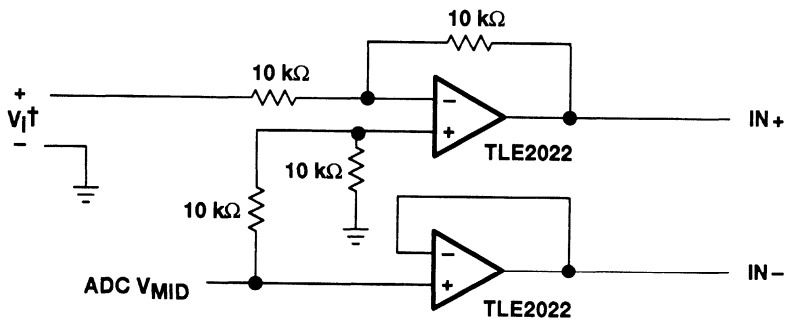
Figure 6-2. Codec Mode (to DSP Interface)

Terminal numbers shown are for the FN package.



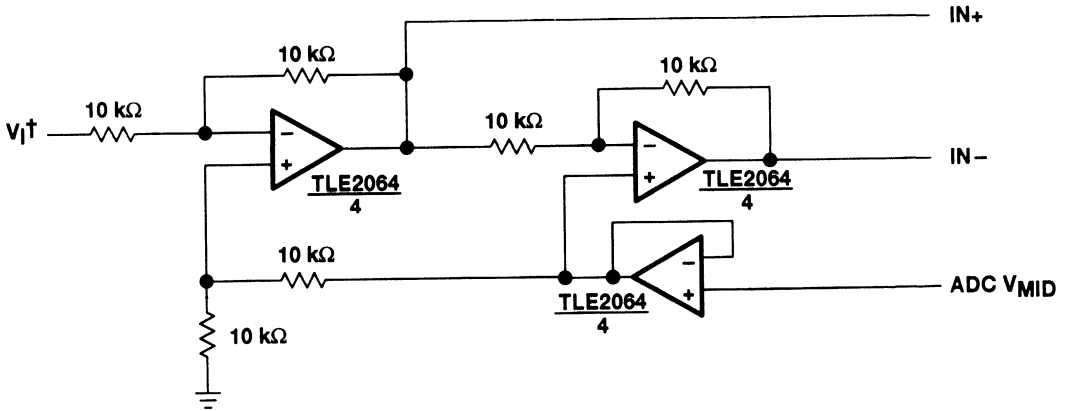
Terminal numbers shown are for the FN package.

Figure 6-3. Master With Slave (to DSP Interface)



† The V_1 source must be capable of sinking a current equal to $[ADC V_{MID} + |V_1|_{(max)}]/10\text{ k}\Omega$.

Figure 6-4. Single-Ended Input (Ground Referenced)



† The V_I source must be capable of sinking a current equal to $[(ADC V_{MID}/2) + |V_I|(\max)]/10\text{ k}\Omega$.

Figure 6-5. Single-Ended to Differential Input (Ground Referenced)

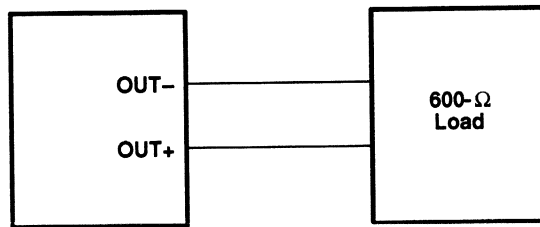
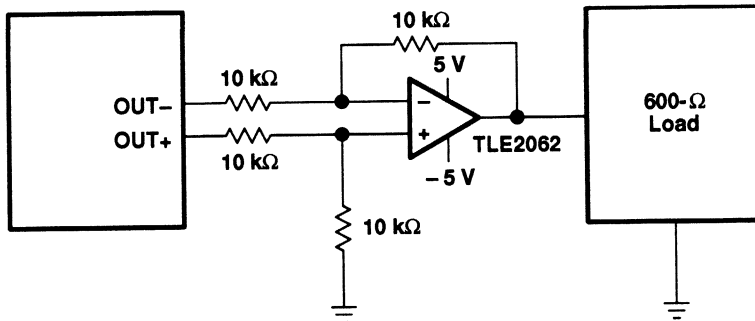


Figure 6-6. Differential Load



NOTE: When a signal changes from a single supply with a nonzero reference system to a grounded load, the operational amplifier must be powered from plus and minus supplies or the load must be capacitively coupled.

Figure 6-7. Differential Output Drive (Ground Referenced)

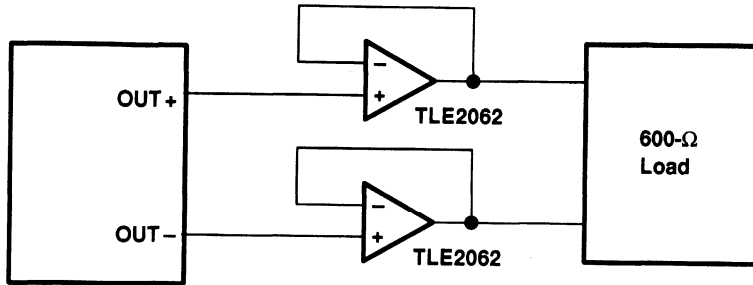
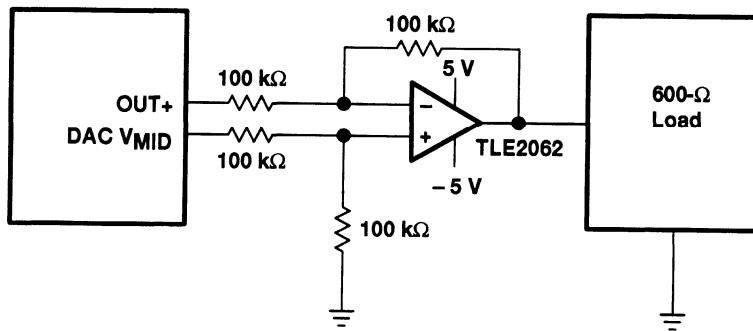


Figure 6-8. Low-Impedance Output Drive



NOTE: When a signal changes from a single supply with a nonzero reference system to a grounded load, the operational amplifier must be powered from plus and minus supplies or the load must be capacitively coupled.

Figure 6-9. Single-Ended Output Drive (Ground Referenced)

Appendix A

Primary Control Bits

The function of the primary-word control bits D01 and D00 and the hardware terminals FC0 and FC1 are shown below. Any combinational state of D01, D00, FC1, and FC0 not shown is ignored.

CONTROL FUNCTION OF CONTROL BITS

BITS		TERMINALS		
D01	D00	FC1	FC0	
0	0	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.
0	0	0	1	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of the next internal \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods equal to the value contained in the A' register. When the A' register value is negative, the internal falling edge of \overline{FS} occurs earlier.
0	0	1	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the rising edge of the next internal \overline{FS} , the next ADC/DAC sample time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, the internal falling edge of \overline{FS} occurs later.
0	0	1	1	On the next falling edge of the primary \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. When FC0 and FC1 are both taken high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS} .
0	1	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of D01 and D00 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, the falling edge of \overline{FS} occurs earlier.
1	0	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of D01 and D00. On the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, the internal falling edge of \overline{FS} occurs later.
1	1	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT. When D00 and D01 are both high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS} .

CONTROL FUNCTION OF CONTROL BITS (Continued)

BITS		TERMINALS		
D01	D00	FC1	FC0	
0	1	1	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>The phase adjustment is determined by the state of D01 and D00 such that on the next rising edge of \overline{FS}, the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs earlier.</p> <p>When FC0 and FC1 are both taken high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p>
1	0	1	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>The phase adjustment is determined by the state of D01 and D00. On the next rising edge of \overline{FS}, the next ADC/DAC sample time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs later.</p> <p>When FC0 and FC1 are both taken high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p>
1	1	1	1	<p>On the next falling edge of the primary \overline{FS}, the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When FC1 and FC0 are both high or D01 and D00 are both high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary \overline{FS} occurs at 1/2 the sampling time measured from the falling edge of the primary \overline{FS}.</p>
1	1	0	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When D00 and D01 are high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p> <p>The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS}, the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs earlier.</p>
1	1	1	0	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When D00 and D01 are high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p> <p>The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS}, the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs earlier.</p>
1	1	1	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When FC1 and FC0 are both high or D01 and D00 are both high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary \overline{FS} occurs at 1/2 the sampling time measured from the falling edge of the primary \overline{FS}.</p>

Appendix B

Secondary Communications

The function of the control bits DS15 and DS14 and the hardware terminals FC0 and FC1 are shown below. Any combinational state of DS15, DS14, FC1, and FC0 not shown is ignored.

CONTROL FUNCTION OF SECONDARY COMMUNICATION

BITS		TERMINALS		
DS15	DS14	FC1	FC0	
0	0	Ignored		On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.
0	1	Ignored		On the next falling edge of the \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of DS15 and DS14 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs earlier.
1	0	Ignored		On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of D01 and D00. On the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs later.
1	1	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.
1	1	0	1	On the next falling edge of the \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs earlier.
1	1	1	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. When the A' register value is negative, \overline{FS} occurs later.
1	1	1	1	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.

Appendix C

TLC320AC01C/TLC320AC02C Specification Comparisons

Texas Instruments manufactures the TLC320AC01C and the TLC320AC02C specified for the 0°C to 70°C commercial temperature range and the TLC320AC02I specified for the -40°C to 85°C temperature range. The TLC320AC02C and TLC320AC02I operate at a relaxed TLC320AC01C specification. The differences are listed in the following tables.

ADC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted) (see Note 1)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = 6\text{ dB}$		$A_V = 12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
TLC320AC01	$V_I = -6\text{ dB to } -1\text{ dB}$	68		—		—		dB
TLC320AC02		64		—		—		
TLC320AC01	$V_I = -12\text{ dB to } -6\text{ dB}$	63		68		—		
TLC320AC02		59		64		—		
TLC320AC01	$V_I = -18\text{ dB to } -12\text{ dB}$	57		63		68		
TLC320AC02		56		59		64		
TLC320AC01	$V_I = -24\text{ dB to } -18\text{ dB}$	51		57		63		
TLC320AC02		50		56		59		
TLC320AC01	$V_I = -30\text{ dB to } -24\text{ dB}$	45		51		57		
TLC320AC02		44		50		56		
TLC320AC01	$V_I = -36\text{ dB to } -30\text{ dB}$	39		45		51		
TLC320AC02		38		44		50		
TLC320AC01	$V_I = -42\text{ dB to } -36\text{ dB}$	33		39		45		
TLC320AC02		32		38		44		
TLC320AC01	$V_I = -48\text{ dB to } -42\text{ dB}$	27		33		39		
TLC320AC02		26		32		38		

NOTE 1: The analog-input test signal is a 1020-Hz sine wave with 0 dB = 6 V peak to peak as the reference level for the analog input signal.

DAC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted) (see Note 2)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = -6\text{ dB}$		$A_V = -12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
TLC320AC01	$V_O = -6\text{ dB to }0\text{ dB}$	68		—		—		dB
TLC320AC02		64		—		—		
TLC320AC01	$V_O = -12\text{ dB to }-6\text{ dB}$	63		68		—		
TLC320AC02		59		64		—		
TLC320AC01	$V_O = -18\text{ dB to }-12\text{ dB}$	57		63		68		
TLC320AC02		56		59		64		
TLC320AC01	$V_O = -24\text{ dB to }-18\text{ dB}$	51		57		63		
TLC320AC02		50		56		59		
TLC320AC01	$V_O = -30\text{ dB to }-24\text{ dB}$	45		51		57		
TLC320AC02		44		50		56		
TLC320AC01	$V_O = -36\text{ dB to }-30\text{ dB}$	39		45		51		
TLC320AC02		38		44		50		
TLC320AC01	$V_O = -42\text{ dB to }-36\text{ dB}$	33		39		45		
TLC320AC02		32		38		44		
TLC320AC01	$V_O = -48\text{ dB to }-42\text{ dB}$	27		33		39		
TLC320AC02		26		32		38		

NOTE 2: The input signal, V_I , is the digital equivalent of a 1020-Hz sine wave (full-scale analog output at full-scale digital input = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT+ to OUT-.

**System Distortion, ADC Channel Attenuation, $V_{DD} = 5\text{ V}$, $f_S = 8\text{ kHz}$,
FCLK = 144 kHz (Unless Otherwise Noted)**

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
TLC320AC01	Second harmonic	Differential input (see Note 3)	70		dB
TLC320AC02			64		dB
TLC320AC01	Third harmonic and higher harmonics		70		dB
TLC320AC02			64		dB

NOTE 3: The input signal is a 1020 Hz-sine wave for the ADC channel. Harmonic distortion is defined for an input level of -1 dB .

**System Distortion, DAC Channel Attenuation, $V_{DD} = 5\text{ V}$, $f_S = 8\text{ kHz}$,
FCLK = 144 kHz (Unless Otherwise Noted)**

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
TLC320AC01	Second harmonic	Differential output (see Note 4)	70		dB
TLC320AC02			64		dB
TLC320AC01	Third harmonic and higher harmonics		70		dB
TLC320AC02			64		dB

NOTE 4: The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT+ to OUT-. Harmonic distortion is specified for a signal input level of 0 dB.

TLC320AC02C, TLC320AC02I ***Data Manual***

Single-Supply Analog Interface Circuit



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1 Introduction

The TLC320AC02[†] analog interface circuit (AIC) is an audio-band processor that provides an analog-to-digital and digital-to-analog input/output interface system on a single monolithic CMOS chip. This device integrates a band-pass switched-capacitor antialiasing input filter, a 14-bit-resolution analog-to-digital converter (ADC), a 14-bit-resolution digital-to-analog converter (DAC), a low-pass switched-capacitor output-reconstruction filter, $(\sin x)/x$ compensation, and a serial port for data and control transfers.

The internal circuit configuration and performance parameters are determined by reading control information into the eight available data registers. The register data are used to set up the device for a given mode of operation and application.

The major functions of the TLC320AC02 are:

1. To convert audio-signal data to digital format by the ADC channel
2. To provide the interface and control logic to transfer data between its serial input and output terminals and a digital signal processor (DSP) or microprocessor
3. To convert received digital data back to an audio signal through the DAC channel

The antialiasing input low-pass filter is a switched-capacitor filter with a sixth-order elliptic characteristic. The high-pass filter is a single-pole filter to preserve low-frequency response as the low-pass filter cutoff is adjusted. There is a three-pole continuous-time filter that precedes this filter to eliminate any aliasing caused by the filter clock signal.

The output-reconstruction switched-capacitor filter is a sixth-order elliptic transitional low-pass filter followed by a second-order $(\sin x)/x$ correction filter. This filter is followed by a three-pole continuous-time filter to eliminate images of the filter clock signal.

The TLC320AC02 consists of two signal-processing channels, an ADC channel and a DAC channel, and the associated digital control. The two channels operate synchronously; data reception at the DAC channel and data transmission from the ADC channel occur during the same time interval. The data transfer is in 2s-complement format.

There are three basic modes of operation available: the stand-alone analog-interface mode, the master-slave mode, and the linear-codec mode. In the stand-alone mode, the TLC320AC02 generates the shift clock and frame synchronization for the data transfers and is the only AIC used. The master-slave mode has one TLC320AC02 as the master that generates the master-shift clock and frame synchronization; the remaining AICs are slaves to these signals. In the linear-codec mode, the shift clock and the frame-synchronization signals are externally generated and the timing can be any of the standard codec-timing patterns.

Typical applications for this device include modems, speech processing, analog interface for DSPs, industrial-process control, acoustical-signal processing, spectral analysis, data acquisition, and instrumentation recorders.

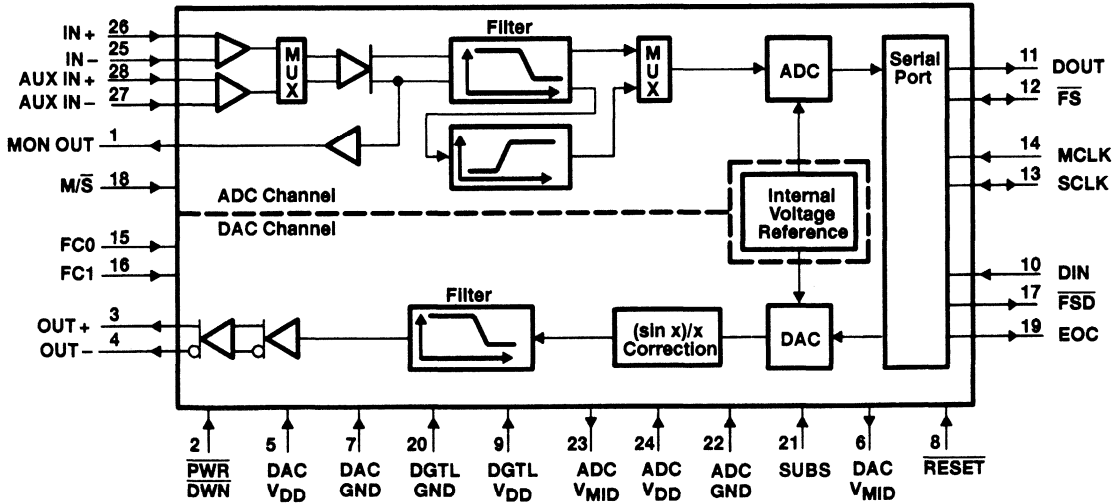
The TLC320AC02I is characterized for operation from -40°C to 85°C , and the TLC320AC02C is characterized for operation from 0°C to 70°C .

[†] The TLC320AC02 is functionally equivalent to the TLC320AC01 and differs only in the electrical specifications as shown in Appendix C.

1.1 Features

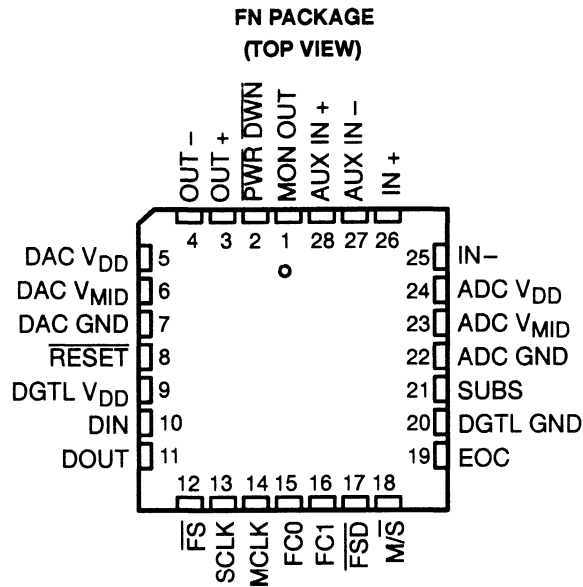
- General-Purpose Signal-Processing Analog Front End (AFE)
- Single 5-V Power Supply
- Power Dissipation . . . 100 mW Typ
- Signal-to-Distortion Ratio . . . 70 dB Typ
- Programmable Filter Bandwidths (up to 10.8 kHz) and Synchronous ADC and DAC Sampling
- Serial-Port Interface
- Monitor Output With Programmable Gains of 0 dB, –8 dB, –18 dB, and Squelch
- Two Sets of Differential Inputs With Programmable Gains of 0 dB, 6 dB, 12 dB, and Squelch
- Differential or Single-Ended Analog Output With Programmable Gains of 0 dB, –6 dB, –12 dB, and Squelch
- Differential Outputs Drive 3-V Peak into a 600- Ω Differential Load
- Differential Architecture Throughout
- 1- μ m Advanced LinEPIC™ Process
- 14-Bit Dynamic-Range ADC and DAC
- 2s-Complement Data Format

1.2 Functional Block Diagram

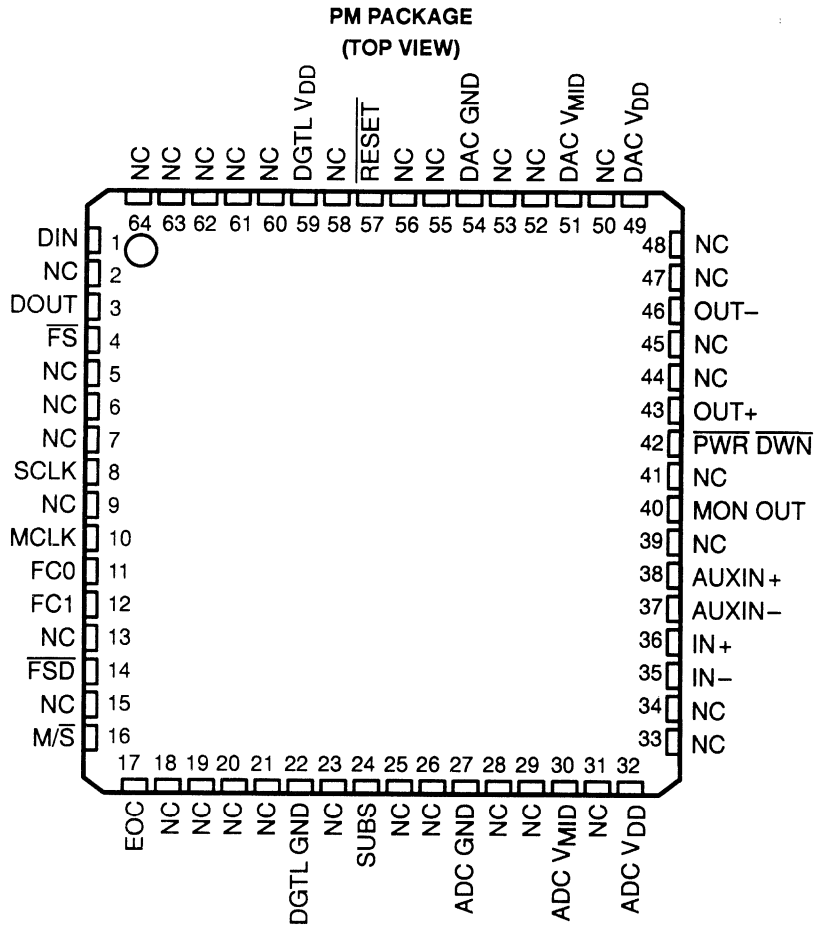


Terminal numbers shown are for the FN package.

1.3 Terminal Assignments



1.3 Terminal Assignments (Continued)



NC – No internal connection

1.4 Terminal Functions

TERMINAL NAME	NO.		I/O	DESCRIPTION
	†	‡		
ADC V _{DD}	24	32	I	Analog supply voltage for the ADC channel
ADC V _{MID}	23	30	O	Midsupply for the ADC channel (requires a bypass capacitor). ADC V _{MID} must be buffered when used as an external reference.
ADC GND	22	27	I	Analog ground for the ADC channel
AUX IN+	28	38	I	Noninverting input to auxiliary analog input amplifier
AUX IN-	27	37	I	Inverting input to auxiliary analog input amplifier
DAC V _{DD}	5	49	I	Digital supply voltage for the DAC channel
DAC V _{MID}	6	51	O	Midsupply for the DAC channel (requires a bypass capacitor). DAC V _{MID} must be buffered when used as an external reference.
DAC GND	7	54	I	Analog ground for the DAC channel
DIN	10	1	I	Data input. DIN is used to receive the DAC input data and command information and is synchronized with SCLK.
DOUT	11	3	O	Data output. This terminal outputs the ADC data results and register read contents. DOUT is synchronized with SCLK.
DGTL V _{DD}	9	59	I	Digital supply voltage for control logic
DGTL GND	20	22	I	Digital ground for control logic
EOC	19	17	O	End-of-conversion output. EOC goes high at the start of the ADC conversion period and low when conversion is complete. EOC remains low until the next ADC conversion period begins and indicates the internal device conversion period.
FC0	15	11	I	Hardware control input. FC0 is used in conjunction with FC1 to request secondary communication and phase adjustments. FC0 should be tied low if it is not used.
FC1	16	12	I	Hardware control input. FC1 is used in conjunction with FC0 to request secondary communication and phase adjustments. FC1 should be tied low if it is not used.
\overline{FS}	12	4	I/O	Frame synchronization. When \overline{FS} goes low, DIN begins receiving data bits and DOUT begins transmitting data bits. In master mode, \overline{FS} is low during the simultaneous 16-bit transmission to DIN and from DOUT. In slave mode, \overline{FS} is externally generated and must be low for one shift-clock period minimum to initiate the data transfer.
FSD	17	14	O	Frame synchronization delayed output. This active-low output is used to synchronize a slave device to the frame synchronization timing of the master device. \overline{FSD} is applied to the slave \overline{FS} input and is the same duration as the master \overline{FS} signal but delayed in time by the number of shift clocks programmed in the \overline{FSD} register.
IN+	26	36	I	Noninverting input to analog input amplifier
IN-	25	35	I	Inverting input to analog input amplifier
MCLK	14	10	I	The master clock input is used to drive all the key logic signals of the AIC.
MON OUT	1	40	O	The monitor output allows monitoring of analog input and is a high-impedance output.
$\overline{M/S}$	18	16	I	Master/slave select input. When $\overline{M/S}$ is high, the device is the master and when low, it is a slave.

† Terminal numbers shown are for the FN package.

‡ Terminal numbers shown are for the PM package.

1.4 Terminal Functions (Continued)

TERMINAL			I/O	DESCRIPTION
NAME	NO.†	NO.‡		
OUT+	3	43	O	Noninverting output of analog output power amplifier. OUT+ can drive transformer hybrids or high-impedance loads directly in a differential connection or a single-ended configuration with a buffered V_{MID} .
OUT-	4	46	O	Inverting output of analog output power amplifier. OUT- is functionally identical with and complementary to OUT+.
$\overline{PWR\ DWN}$	2	42	I	Power-down input. When $\overline{PWR\ DWN}$ is taken low, the device is powered down such that the existing internally programmed state is maintained. When $\overline{PWR\ DWN}$ is brought high, full operation resumes.
\overline{RESET}	8	57	I	Reset input that initializes the internal counters and control registers. \overline{RESET} initiates the serial data communications, initializes all of the registers to their default values, and puts the device in a preprogrammed state. After a low-going pulse on \overline{RESET} , the device registers are initialized to provide a 16-kHz data-conversion rate and 7.2-kHz filter bandwidth for a 10.368-MHz master clock input signal.
SCLK	13	8	I/O	Shift clock. SCLK clocks the digital data into DIN and out of DOUT during the frame-synchronization interval. When configured as an output (M/\overline{S} high), SCLK is generated internally by dividing the master clock signal frequency by four. When configured as an input (M/\overline{S} low), SCLK is generated externally and synchronously to the master clock. This signal is used to clock the serial data into and out of the device.
SUBS	21	24	I	Substrate connection. SUBS should be tied to ADC GND.

† Terminal numbers shown are for the FN package.

‡ Terminal numbers shown are for the PM package.

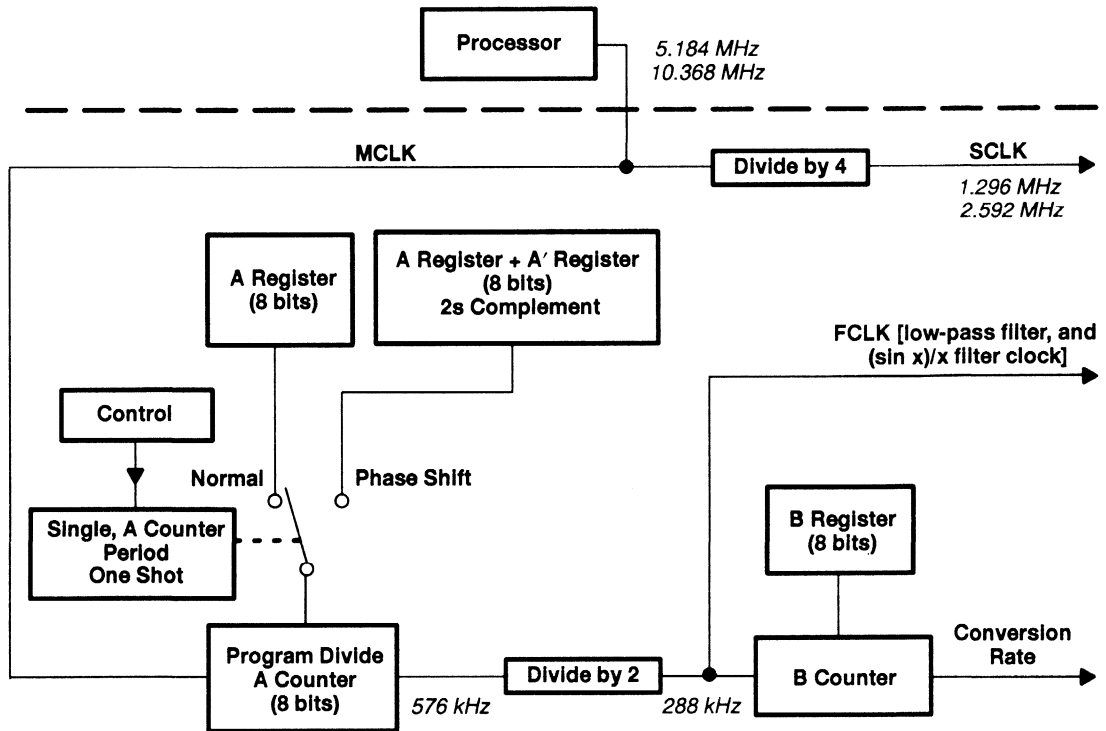


Figure 1-1. Control Flow Diagram

Table 1-1. Operating Frequencies

FCLK (kHz)	LOW-PASS FILTER BANDWIDTH (kHz)	B REGISTER CONTENTS (Program No. of Filter Clocks) (Decimal)	CONVERSION RATE (kHz)	HIGH-PASS POLE FREQUENCY (Hz)
144	3.6	20 (see Note 1)	7.2	36
		18	8	40
		15	9.6	48
		10 (see Note 2)	14.4	72
288	7.2	20 (see Note 1)	14.4	72
		18	16	80
		15	19.2	96
		10 (see Notes 2 and 3)	28.8	144
432	10.8	20 (see Note 1)	21.6	108
		18	24	120
		15 (see Note 3)	28.8	144
		10 (see Notes 2 and 3)	43.2	216

- NOTES: 1. The B register can be programmed for values greater than 20; however, since the sample rate is lower than 7.2 kHz and the internal filter remains at 3.6 kHz, an external antialiasing filter is required.
2. If the B register is programmed for a value less than 10, the ADC and the DAC conversions are not completed before the next frame-sync signal and the results are in error.
3. The maximum sampling rate for the ADC channel is 43.2 kHz. The maximum rate for the DAC channel is 25 kHz.

1.5 Register Functional Summary

There are nine data registers that are used as follows:

- Register 0 The No-op register. The 0 register allows phase adjustments to be made without reprogramming a data register.
- Register 1 The A register controls the count of the A counter.
- Register 2 The B register controls the count of the B counter.
- Register 3 The A' register controls the phase adjustment of the sampling period. The adjustment is equal to the register value multiplied by the input master period.
- Register 4 The amplifier gain-select register controls the gains of the input, output, and monitor amplifiers.
- Register 5 The analog control configuration register controls:
- The addition/deletion of the high-pass filter to the ADC signal path
 - The enable/disable of the analog loopback
 - The selection of the regular inputs or auxiliary inputs
 - The function that allows processing of signals that are the sum of the regular inputs and the auxiliary inputs ($V_{IN} + V_{AUX IN}$).
- Register 6 The digital configuration register controls:
- Selection of the free-run function
 - \overline{FSD} [frame-synchronization (sync) delay] output enable/disable
 - Selection of 16-bit function
 - Forcing secondary communications
 - Software reset
 - Software power down
- Register 7 The frame-sync delay register controls the time delay between the master-device frame sync and slave-device frame sync. Register 7 must be the last register programmed when using slave devices since all register data is latched and valid on the 16th falling edge of SCLK. On the 16th falling edge of SCLK, all delayed frame-sync intervals are shifted by this programmed amount.
- Register 8 The frame-sync number register informs the master device of the number of slaves that are connected in the chain.

2 Detailed Description

2.1 Definitions and Terminology

ADC Channel	All signal processing circuits between the analog input and the digital conversion results at DOUT
Codec Mode	The operating mode under which the device receives shift clock and frame-sync signals from a host processor. The device has no slaves.
d	The d represents valid programmed or default data in the control register format (see Section 2.19, Secondary Serial Communications) when discussing other data-bit portions of the register.
Dxx	Bit position in the primary data word (xx is the bit number)
DAC Channel	All signal processing circuits between the digital data word applied to DIN and the differential output analog signal available at OUT+ and OUT–
Data Transfer Interval	The time during which data is transferred from DOUT and to DIN. This interval is 16 shift clocks regardless of whether the shift clock is internally or externally generated. The data transfer is initiated by the falling edge of the frame-sync signal.
DSxx	Bit position in the secondary data word (xx is the bit number)
FCLK	An internal clock frequency that is a division of MCLK that controls the low-pass filter and (sinx)/x filter clock (see Figure 1–1 and Table 1–1).
f _i	The analog input frequency of interest
Frame Sync	The falling edge of the signal that initiates the data-transfer interval. The primary frame sync starts the primary communications, and the secondary frame sync starts the secondary serial communications.
Frame Sync and Sampling Period	The time between falling edges of successive primary frame-sync signals
Frame-Sync Interval	The time period occupied by 16 shift clocks. Regardless of the mode of operation, there is always an internal frame-sync interval signal that goes low on the rising edge of SCLK and remains low for 16 shift clocks. It is used for synchronization of the serial-port internal signals. It goes high on the 17th rising edge of SCLK.
f _s	The sampling frequency that is the reciprocal of the sampling period
Host	Any processing system that interfaces to DIN, DOUT, SCLK, or \overline{FS}
Master Mode	The operating mode under which the device generates and uses its own shift clock and frame-sync signal and generates all delayed frame-sync signals necessary to support slave devices
Phase Adjustment	The programmed time variation from the falling edge of one frame-sync signal to the falling edge of the next frame sync signal. The time variation is determined by the contents of the A' register. Since the time between falling edges of successive frame sync signals is the the sampling period, the sampling period is adjusted.
Primary (Serial) Communications	The digital data-transfer interval. Since the device is synchronous, the signal data words from the ADC channel and to the DAC channel occur simultaneously.
Secondary (Serial) Communications	The digital control and configuration data-transfer interval into DIN and the register read-data cycle from DOUT. The data-transfer interval occurs when requested by hardware or software.
Signal Data	The input signal and all of the converted representations through the ADC channel and return through the DAC channel to the analog output. This is contrasted with the purely digital software control data.

Slave Mode	The operating mode under which the device receives shift clock and frame-sync signals from a master device
Stand-Alone Mode	The operating mode under which the device generates and uses its own shift clock and frame-sync signal. The device has no slave devices.
X	The X represents a don't care bit position within the control register format

2.2 Reset and Power-Down Functions

2.2.1 Reset

The TLC320AC02 resets both the internal counters and registers, including the programmed registers, by any of the following:

- Applying power to the device, causing a power-on reset (POR)
- Applying a low reset pulse to $\overline{\text{RESET}}$
- Reading in the programmable software reset bit (DS01 in register 6)

$\overline{\text{PWR DWN}}$ resets the counters only and preserves the programmed register contents.

2.2.2 Conditions of Reset

The two internal reset signals used for the reset and synchronization functions are as follows:

1. Counter reset: this signal resets all flip-flops and latches that are not externally programmed with the exception of those generating the reset pulse itself. In addition, this signal resets the software power-down bit.

Counter reset = power-on reset + $\overline{\text{RESET}}$ + RESET bit + $\overline{\text{PWR DWN}}$

2. Register reset: this signal resets all flip-flops and latches that are not reset by the counter reset except those generating the reset pulse itself.

Register reset = power-on reset + $\overline{\text{RESET}}$ + RESET bit

Both reset signals are at least one master clock period long and release on the falling edge of the master clock.

2.2.3 Software and Hardware Power Down

Given the definitions and conditions of $\overline{\text{RESET}}$, the software-programmed power-down condition is cleared by resetting the software bit (DS00 in register 6) to zero. It is also cleared by either cycling the power to the device, bringing $\overline{\text{PWR DWN}}$ low, or bringing $\overline{\text{RESET}}$ low.

$\overline{\text{PWR DWN}}$ powers down the entire chip (< 1 mA). The software-programmable power-down bit only powers down the analog section of the chip (< 3 mA), which allows a software power-up function. Cycling $\overline{\text{PWR DWN}}$ high to low and back to high resets all flip-flops and latches that are not externally programmed, thereby preserving the register contents.

If $\overline{\text{PWR DWN}}$ is not used, it should be tied high.

2.2.4 Register Default Values After POR, Software Reset, or $\overline{\text{RESET}}$ Is Applied

Register 1 – The A Register

The default value of the A-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

Register 2 – The B Register

The default value of the B-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

Register 3 – The A' Register

The default value of the A'-register data is decimal 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

Register 4 – The Amplifier Gain-Select Register

The default value of the amplifier gain-select register data is shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	1	0	1

Register 5 – The Analog Control Configuration Register

The power-up and reset conditions are as shown below. In the read mode, eight bits are read but the four LSBs are repeated as the four MSBs.

DS03	DS02	DS01	DS00
0	1	0	1

Register 6 – The Digital Configuration Register

The default value of DS07 – DS00 is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

Register 7 – The Frame-Sync Delay Register

The default value of DS07 – DS00 is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

Register 8 – The Frame-Sync Number Register

The default value of DS07 – DS00 is 1 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	1

2.3 Master-Slave Terminal Function

Table 2–1 describes the function of the master/slave (M/\overline{S}) input. The only difference between master and slave operations in the TLC320AC02 is that SCLK and \overline{FS} are outputs when M/\overline{S} is high and inputs when M/\overline{S} is low.

Table 2–1. Master-Slave Selection

MODE	M/\overline{S}^\dagger	\overline{FS}	SCLK
Master and Stand-Alone	H	Output	Output
Slave and Codec Emulation	L	Input	Input

[†] If the stand-alone mode is desired or if the device is permanently in the master mode, M/\overline{S} must be high.

2.4 ADC Signal Channel

To produce excellent common-mode rejection of unwanted signals, the analog signal is processed differentially until it is converted to digital data. The signal is amplified by the input amplifier at one of three software-selectable gains (typically 0 dB, 6 dB, or 12 dB). A squelch mode can also be programmed for the input amplifier.

The amplifier output is filtered and applied to the ADC input. The ADC converts the signal into discrete digital words in 2s-complement format corresponding to the analog-signal value at the sampling time. These 16-bit digital words, representing sampled values of the analog input signal, are clocked out of the serial port, (DOUT), one word for each primary communication interval. During secondary communications, the data previously programmed into the registers can be read out with the appropriate register address and with the read bit set to 1. If no register read is requested, all 16 bits are 0.

2.5 DAC Signal Channel

DIN receives the 16-bit serial data word (2s complement) from the host during the primary communications interval and latches the data on the 17th rising edge of SCLK. The data are converted to an analog voltage by the DAC with a sample and hold and then through a $(\sin x)/x$ correction circuit and a smoothing filter. An output buffer with three software-programmable gains (0 dB, –6 dB, and –12 dB), as shown in Section 2.20.5, Register 4 (Amplifier Gain-Select Register), drives the differential outputs OUT+ and OUT–. A squelch mode can also be programmed for the output buffer. During secondary communications, the configuration program data are read into the device control registers.

2.6 Serial Interface

The digital serial interface consists of the shift clock, the frame-synchronization signal, the ADC-channel data output, and the DAC-channel data input. During the primary 16-bit frame-synchronization interval, the SCLK transfers the ADC channel results from DOUT and transfers 16-bit DAC data into DIN.

During the secondary frame-synchronization interval, the SCLK transfers the register read data from DOUT if the read bit is set to a one. In addition, the SCLK transfers control and device parameter information into DIN. The functional sequence is shown in Figure 2–1.

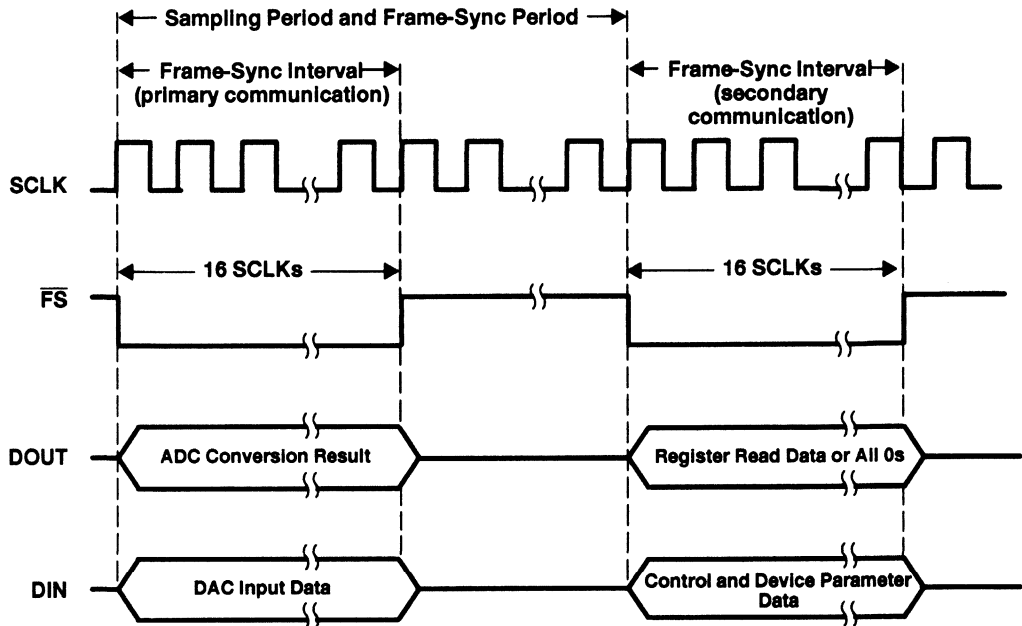


Figure 2–1. Functional Sequence for Primary and Secondary Communication

2.7 Number of Slaves

The number of slaves is determined by the sum of the individual device delays from the frame-sync (\overline{FS}) input low to the frame-sync delayed (\overline{FSD}) low for all slaves as follows:

$$(n) \times tp(FS - FSD) < 1/2 \text{ shift-clock period}$$

Where:

n is the number of slave devices.

Example:

From the above equation, the number of slaves is given by:

$$(n) \leq \frac{1}{2} \times (\text{SCLK period}) \times \frac{1}{tp(FS - FSD)}$$

and assuming the shift clock is 2.4 MHz and $tp(FS - FSD)$ is 40 ns, then the number of slaves is:

$$n \leq \frac{1}{2.4 \text{ MHz}} \times \frac{1}{2} \times \frac{1}{40 \text{ ns}} = \frac{1000}{192} = 5.2$$

The maximum number of slaves under these conditions is five. As the SCLK increases in frequency, the number of slaves that can be used decreases.

2.8 Operating Frequencies

2.8.1 Master and Stand-Alone Operating Frequencies

The sampling (conversion) frequency is derived from the master clock (MCLK) input by the following equation:

$$f_s = \text{Sampling (conversion) frequency} = \frac{\text{MCLK}}{(\text{A register value}) \times (\text{B register value}) \times 2}$$

The inverse is the time between the falling edges of two successive primary frame synchronization signals. The input and output data clock (SCLK) is given by:

$$\text{SCLK frequency} = \frac{\text{MCLK frequency}}{4}$$

2.8.2 Slave and Codec Operating Frequencies

The slave and codec conversion and the data frequencies are determined by the externally applied SCLK and $\overline{\text{FS}}$ signals.

2.9 Switched-Capacitor Filter Frequency (FCLK)

The filter clock (FCLK) is an internal clock signal that is used to determine the filter band-pass frequency and is the B counter clock. The frequency of the filter clock is derived by the following equation:

$$\text{FCLK} = \frac{\text{MCLK}}{(\text{A register value}) \times 2}$$

2.10 Filter Bandwidths

The low-pass (LP) filter -3 dB corner is derived by:

$$f(\text{LP}) = \frac{\text{FCLK}}{40} = \frac{\text{MCLK}}{40 \times (\text{A register value}) \times 2}$$

The high-pass (HP) filter -3 dB corner is derived by:

$$f(\text{HP}) = \frac{\text{Sampling frequency}}{200} = \frac{\text{MCLK}}{200 \times 2 \times (\text{A register value}) \times (\text{B register value})}$$

2.11 Required Minimum Number of MCLK Periods

The number of MCLKs necessary for proper operation if only the primary communications are used is:

$$\begin{aligned} \text{Total number of MCLKs} &= (16 + 2) \text{ SCLKs} \times 4 \text{ MCLKs per SCLK} \\ &= 72 \text{ MCLKs minimum} \end{aligned}$$

The number of MCLKs necessary for proper operation if both the primary and secondary communications are used is:

$$\begin{aligned} \text{Total number of MCLKs} &= (16 + 2) \text{ SCLKs} \times 2 \times 4 \text{ MCLKs per SCLK} \\ &= 144 \text{ MCLKs minimum} \end{aligned}$$

Even though the TLC320AC02 can perform with this number of MCLKs, the host may need more time to execute the required software instructions between primary and secondary communication intervals.

2.12 Master and Stand-Alone Modes

The difference between the master and stand-alone modes is that in the stand-alone mode there are no slave devices. Functionally these two modes are the same. In both, the AIC internally generates the shift clock and frame-sync signal for the serial communications. These signals and the filter clock (FCLK) are derived from the input master clock. The master clock applied at the MCLK input determines the internal device timing. The shift clock frequency is a divide-by-four of the master clock frequency and shifts both the

input and output data at DIN and DOUT, respectively, during the frame-sync interval (16 shift clocks long). To begin the communication sequence, the device is reset (see Section 2.2.1, Reset), and the first frame sync occurs approximately 648 master clocks after the reset condition disappears.

2.12.1 Register Programming

All register programming occurs during secondary communications, and data is latched and valid on the 16th falling edge of SCLK. After a reset condition, eight primary and secondary communications cycles are required to set up the eight programmable registers. Registers 1 through 8 are programmed in secondary communications intervals 1 through 8, respectively. If the default value for a particular register is desired, that register does not need to be addressed during the secondary communications. The no-op command addresses the pseudo-register (register 0), and no register programming takes place during this communication. The no-op command allows phase shifts of the sampling period without reprogramming any register.

During the eight register programming cycles, DOUT is in the high-impedance state. DOUT is released on the rising edge of the eighth primary internal frame-sync interval. In addition, each register can be read back during DOUT secondary communications by setting the read bit to 1 in the appropriate register. Since the register is in the read mode, no data can be written to the register during this cycle. To return this register to the write mode requires a subsequent secondary communication (see Section 2.19, Secondary Serial Communications for detailed register description).

2.12.2 Master and Stand-Alone Functional Sequence

The A counter counts according to the contents of the A register, and the A counter frequency is divided by two to produce the filter clock (FCLK). The B counter is clocked by FCLK with the following functional sequence:

1. The B counter starts counting down from the B register value minus one. Each count remains in the counter for one FCLK period including the zero count. This total counter time is referred to as the B cycle. The end of the zero count is called the end of B cycle.
2. When the B counter gets to a count of nine, the A-to-D conversion starts.
3. The A-to-D conversion is complete ten FCLK periods later.
4. \overline{FS} goes low on a rising edge of SCLK after the A-to-D conversion is complete. That rising edge of SCLK must be preceded by a falling edge of SCLK, which is the first falling edge to occur after the end of B cycle.
5. The D-to-A conversion cycle begins on the rising edge of the internal frame-sync interval and is complete ten FCLK periods later.

2.13 Slave and Codec Modes

The only difference between the slave and codec modes is that the codec mode is controlled directly by the host and does not use a delayed frame-sync signal. In these modes, the shift clock and the frame sync are both externally generated and must be synchronous with MCLK. The conversion frequency is set by the time interval of externally applied frame sync falling edges except when the free-run function is selected by bit 5 of register 6 (see Section 2.15.4, Free-Run Mode). The slave device or devices share the shift clock generated by the master device but receive the frame sync from the previous slave in the chain. The Nth slave \overline{FS} receives the (N-1)st slave \overline{FSD} output and so on. The first slave device in the chain receives \overline{FSD} from the master.

2.13.1 Slave and Codec Functional Sequence

The A counter counts according to the contents of the A register, and the A counter frequency is divided by two to produce the filter clock (FCLK). The device function in the slave or codec mode is the same as steps 1 through 3 of the B cycle description in the master mode but differs as follows:

1. Same as master
2. Same as master
3. Same as master
4. All internal clocks stop 1/2 FCLK before the end of count 0 in the B counter cycle.
5. All internal clocks are restarted on the first rising edge of MCLK after the external \overline{FS} input goes low. This operation provides the synchronization necessary when using an external \overline{FS} signal.
6. The D-to-A conversion starts on the rising edge of the internally generated frame-sync interval at the end of the 16-shift clock data transfer.

In the slave mode, the master controls the phase adjustments for itself and all slaves since all devices are programmed in the same frame-sync interval. In the codec mode, the shift clock and frame sync are externally generated and provide the timing for the ADC and DAC if the free-run function has not been selected (see Section 2.15.4, Free-Run Mode). In the codec mode, there is usually no need for phase adjustments; however, any required phase adjustments must be made by adjusting the external frame-sync timing (sampling time).

2.13.2 Slave Register Programming

When slave devices are used on power up or reset, all slave frame-sync signals occur at the same time as the master frame-sync signal and all slave devices are programmed during the master secondary frame-sync interval with the same data as the master. The last register programmed must be the frame-sync delay (FSD) register because the delay starts immediately on the rising edge of the 17th shift clock of that frame-sync interval. After the FSD register programming is completed for the master and slave, the slave primary frame interval is shifted in time (time slot allocated) according to the data contained in the slave FSD registers. The master then generates frame-sync intervals for itself and each slave to synchronize the host serial port for data transfers for itself and all slave devices.

The number of slaves is specified in the frame-sync number (FSN) register (register 8); therefore, the number of frame-sync intervals generated by the master is equal to the number of slaves plus one (see Section 2.7, Number of Slaves). These master frame-sync intervals are separated in time by the delay time specified by the FSD register (register 7). These master-generated intervals are the only frame-sync interval signals applied to the host serial port to provide the data transfer time slot for the slave devices.

2.14 Terminal Functions

2.14.1 Frame-Sync Function

The frame-sync signal is used to indicate that the device is ready to send and receive data for both master and slave modes. The data transfer begins on the falling edge of the frame-sync signal.

2.14.1.1 Frame Sync (\overline{FS}), Master Mode

The frame sync is generated internally. \overline{FS} goes low on the rising edge of SCLK and remains low for the 16-bit data transfer. In addition to generating its own frame-sync interval, the master also outputs a frame sync for each slave that is being used.

2.14.1.2 Frame-Sync Delayed ($\overline{\text{FSD}}$), Master Mode

For the master, the frame-sync delayed output occurs 1/2 shift-clock period ahead of $\overline{\text{FS}}$ to compensate for the time delay through the master and slave devices. The timing relationships are as follows:

1. If the FSD register data is 0, then $\overline{\text{FSD}}$ goes low on the falling edge of SCLK and prior to the rising edge of SCLK when $\overline{\text{FS}}$ goes low (see Figure 4–4).
2. If the FSD register data is greater than 16, then $\overline{\text{FSD}}$ goes low on a rising edge of SCLK that is the FSD register number of SCLKs after the falling edge of $\overline{\text{FS}}$.

Register data values from 1 to 16 result in the default register value of zero.

2.14.1.3 Frame Sync ($\overline{\text{FS}}$), Slave Mode

The frame-sync timing is generated externally, applied to $\overline{\text{FS}}$, and controls the ADC and DAC timing (see Section 2.15.4, Free-Run Mode). The external frame-sync width must be a minimum of one shift clock to be recognized and can be as long as 16 shift clocks.

2.14.1.4 Frame-Sync Delayed ($\overline{\text{FSD}}$), Slave Mode

This output is fed from the master to the first slave and the first slave $\overline{\text{FSD}}$ output to the second and so on down the chain. The FSD timing sequence in the slave mode is as follows:

1. If the FSD register data is 0, then $\overline{\text{FSD}}$ goes low after $\overline{\text{FS}}$ goes low (see Figure 4–5).
2. When the FSD register data is greater than 16, $\overline{\text{FSD}}$ goes low on a rising edge of SCLK that is the FSD register number of SCLKs after the falling edge of $\overline{\text{FS}}$.

Data values from 1 to 16 are constrained because the data transfer requires 16 clock periods.

2.14.2 Data Out (DOUT)

DOUT is placed in the high-impedance state on the 17th rising edge of SCLK (internal or external) after the falling edge of frame sync. In the primary communication, the data word is the ADC conversion result. In the secondary communication, the data is the register-read results when requested by the read/write ($\text{R}/\overline{\text{W}}$) bit with the eight MSBs set to zero (see the Serial Communications section). If no register read is requested, the secondary word is all zeroes.

2.14.2.1 Data Out, Master Mode

In the master mode, DOUT is taken from the high-impedance state by the falling edge of frame sync. The most significant data bit then appears on DOUT.

2.14.2.2 Data Out, Slave Mode

In the slave mode, DOUT is taken from the high-impedance state by the falling edge of the external frame sync or the rising edge of the external SCLK, whichever occurs first (see Figure 4–7). The falling edge of frame sync can occur $\pm 1/4$ SCLK period around the SCLK rising edge (see Figure 4–3). The most significant data bit then appears on DOUT.

2.14.3 Data In (DIN)

In the primary communication, the data word is the digital input signal to the DAC channel. In the secondary communication, the data is the control and configuration data to set up the device for a particular function (see Section 2.16, Serial Communications).

2.14.4 Hardware Program Terminals (FC1 and FC0)

These inputs provide for hardware programming requests for secondary communication or phase adjustment. These inputs work in conjunction with the control bits D01 and D00 of the primary data word or control bits DS15 and DS14 of the secondary data word. The data on FC1 and FC0 are latched on the rising edge of the next internally generated primary or secondary frame-sync interval. These inputs should be tied low if not used (see Section 2.17, Request for Secondary Serial Communication and Table 2–3).

2.14.5 Midpoint Voltages (ADC V_{MID} and DAC V_{MID})

Since the device operates at a single-supply voltage, two midpoint voltages are generated for internal signal processing. ADC V_{MID} is used for the ADC channel reference, and DAC V_{MID} is used for the DAC channel reference. Two references are used to minimize channel-to-channel noise and crosstalk. ADC V_{MID} and DAC V_{MID} must be buffered if used as a reference for external signal processing.

2.15 Device Functions

2.15.1 Phase Adjustment

In some applications, such as modems, the device sampling period may require an adjustment to synchronize with the incoming bit stream to improve the signal-to-noise ratio. The TLC320AC02 can adjust the sampling period through the use of the A' register and the control bits.

2.15.1.1 Phase-Adjustment Control

A phase adjustment is a programmed variation in the sampling period. A sampling period is adjusted according to the data value in the A' register, and the phase adjustment is that number of master clocks (MCLK). An adjustment is made during device operation with data bits D01 and D00 in the primary communication, with data bits DS15 and DS14 in the secondary word or in combination with the hardware pins FC1 and FC0 (see Table 2–3). This adjustment request is latched on the rising edge of the next internal frame-sync interval and is only valid for the next sampling period. To repeat the phase adjustment, another phase request must be initiated.

2.15.1.2 Use of the A' Register for Phase Adjustment

The A' register value is used to make slight timing adjustments to the sampling period. The sampling period increases or decreases according to the sign of the programmed A' register value and the state of data bits D01 and D00 in the primary data word.

The general equation for the conversion frequency is given as:

$$f_s = \text{conversion frequency} = \frac{\text{MCLK}}{(2 \times \text{A register value} \times \text{B register value}) \pm (\text{A' register value})}$$

Therefore, if A' = 0, the device conversion (sampling) frequency and period is constant.

If a nonzero A' value is programmed, the sampling frequency and period responds as shown in Table 2–2.

Table 2–2. Sampling Variation With A'

D01	D00	SIGN OF THE A' REGISTER VALUE	
		PLUS VALUE (+)	NEGATIVE VALUE (-)
0	1 (increase command)	Frequency decreases, period increases	Frequency increases, period decreases
1	0 (decrease command)	Frequency increases, period decreases	Frequency decreases, period increases

An adjustment to the sampling period, which must be requested through D01 and D00 of the primary data word to DIN, is valid for the following sampling period only. If the adjustment is required for the subsequent sampling period, it must be requested again through D01 and D00 of the primary data word. For each request, only the sampling period occurring immediately after the primary data word request is affected.

The amount of time shift in the entire sampling period ($1/f_s$) is as follows:

If the sampling period is set to 125 μ s (8 kHz), the A' register is loaded with decimal 10 and the TLC320AC02 master clock frequency is 10.386 MHz. The amount of time each sampling period is increased or decreased, when requested, is:

$$\text{Time shift} = (\text{A' register value}) \times (\text{MCLK period})$$

The device changes the entire sampling period by only the MCLK period times the A' register value.

$$\begin{aligned} \text{Change in sampling period} &= \text{contents of A' register} \times \text{master clock period} \\ &= 10 \times 96.45 \text{ ns} = 964 \text{ ns (less than 1\% of the sampling period)} \end{aligned}$$

The sampling period changes by 964.5 ns each time the phase adjustment is requested by the primary data word (i.e., once per sampling period).

It is evident then that the change in sampling period is very small compared to the sampling period. To observe this effect over a long period of time ($>$ sampling period), this change must be continuously requested by the primary data word. If the adjustment is not requested again, the sampling period changes only once and it may appear that there was no execution of the command. This is especially true when bench testing the device. Automatic test equipment can test for results within a single sampling period.

Internally, the A' register value only affects one cycle (period) of the A counter. The A and A' values are additive, but only for one A-counter period. The A counter begins the first count at the default or programmed A-register value and counts down to the A'-register value. As the A' value increases or decreases, the first clock cycle from the A counter is lengthened or shortened. The initial A-counter period is the only counter period affected by the A' register such that only this single period is increased or decreased.

2.15.2 Analog Loopback

This function allows the circuit to be tested remotely. In loopback, OUT+ and OUT- are internally connected to IN+ and IN-. The DAC data bits D15 to D02 that are applied to DIN can be compared with the ADC output data bits D15 to D02 at DOUT. There are some differences due to the ADC and DAC channel offset. The loopback function is implemented by setting DS01 and DS00 to zero in control register 5 (see Section 2.19, Secondary Serial Communications).

2.15.3 16-Bit Mode

In the 16-bit mode, the device ignores the last two control bits (D01 and D00) of the primary word and requests continual secondary communications to occur. By ignoring the last two primary communication bits, compatibility with existing 16-bit software can be maintained. This function is implemented by setting bit DS03 to one in register 6. To return to normal operation, DS03 must be reprogrammed to zero.

2.15.4 Free-Run Mode

With the free-run bit set in register 6, the external shift clock and frame sync control only the data transfer. The ADC and DAC timing are controlled by the A and B register values, and the phase-shift adjustment must be done as if the device is in stand-alone mode (by the software or state of FC1 and FC0).

Phase adjustment cannot be made by adjustment of the frame-sync timing. The external frame sync must occur within 1/2 FCLK period of the internal frame sync (FCLK as determined by the values of the A and B registers).

If the external frame sync occurs simultaneously with the internal load, the data-transfer request by the external frame sync takes precedence over the internal load command. The latching of the ADC conversion data in the output register is inhibited until the current 16 bits are shifted out of the register by the shift clock.

2.15.5 Force Secondary Communication

With bit 2 in register 6 set to 1, secondary communication is requested continuously. It overrides all software and hardware requests concerning secondary communication. Phase shifting, however, can still be performed with the software and hardware.

2.15.6 Enable Analog Input Summing

By setting bits DS01 and DS00 to 11 in register 5, the normal analog input voltage is summed with the auxiliary input voltage. The gain for the analog input amplifier is set by data bits DS03 and DS02 in register 4.

2.15.7 DAC Channel (sin x)/x Error Correction

The (sin x)/x compensation filter is designed for zero (sin x)/x error using a B-register value of 15. Since the filter cannot be removed from the signal path, operation using another B-register value results in an error in the reconstructed analog output. The error is given by the following equation. Any error compensation needed by a given application can be performed in the software.

$$\text{DAC channel frequency response error} = 20 \times \log_{10} \left[\frac{\sin \left(\frac{2\pi \times A \times B}{f_{\text{MCLK}}} \times f \right)}{\sin \left(\frac{30\pi \times A}{f_{\text{MCLK}}} \times f \right)} \times \frac{15}{B} \right]$$

where:

- f = the frequency of interest
- f_{MCLK} = the TLC320AC02 master clock frequency
- A = the A-register value
- B = the B-register value

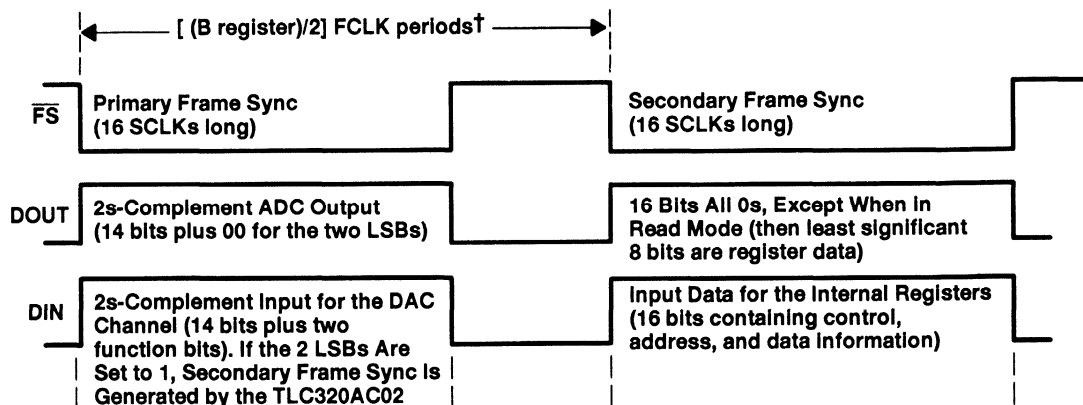
and the arguments of the sin functions are in radians.

2.16 Serial Communications

2.16.1 Stand-Alone and Master-Mode Word Sequence and Information Content During Primary and Secondary Communications

For the stand-alone and master modes, the sequence in Figure 2–2 shows the relationship between the primary and secondary communications interval, the data content into DIN, and the data content from DOUT.

The TLC320AC02 can provide a phase-shift command or the next secondary communications interval by decoding 1) the programmed state of the FC1 and FC0 inputs and the D01 and D00 data bits in the primary data word or 2) the state of the FC1 and FC0 inputs and the DS15 and DS14 data bits in the secondary data word (see Table 2–3). If DS13 (the R \overline{W} bit) is the default value of zero, all 16 bits from DOUT are 0 during secondary communication. However, when the R \overline{W} bit is set to one in the secondary communication control word, the secondary transmission from DOUT still contains 0s in the eight MSBs. The lower order eight bits contain the data of the register currently being addressed. This function provides register status information for the host.

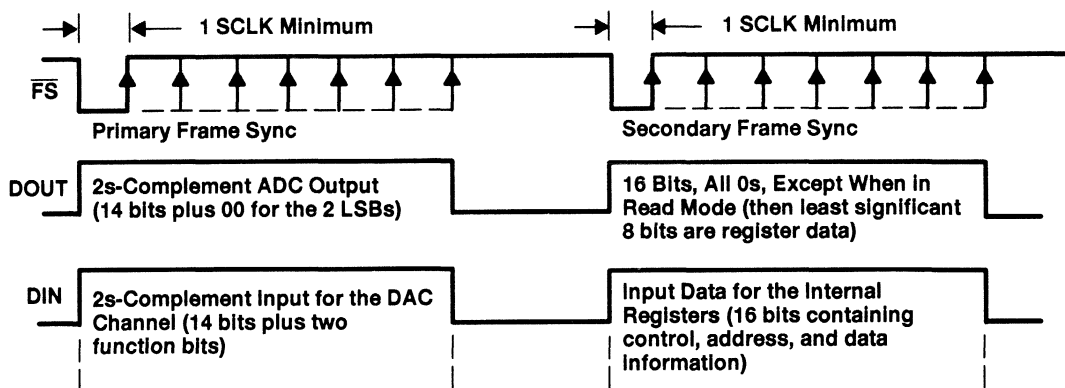


† The time between the primary and secondary frame sync is the time equal to FCLK period multiplied by the B-register contents. The time interval is rounded to the nearest shift clock. The secondary frame-sync signal goes from high to low on the next shift clock low-to-high transition after (B register/2) filter clock periods.

Figure 2–2. Master and Stand-Alone Functional Sequence

2.16.2 Slave- and Codec-Mode Word Sequence and Information Content During Primary and Secondary Communications

For the slave and codec modes, the sequence is basically the same as the stand-alone and master modes with the exception that the frame sync and the shift clock are generated and controlled externally as shown in Figure 2–3. For the codec mode, the frame-sync pulse width needs to be a minimum of one shift clock long. The timing relationship between the frame sync and shift clock is shown in the timing diagrams. Phase shifting is usually not required in the slave or codec mode because the frame-sync timing can be adjusted externally if required.



NOTE: The time between the primary and secondary frame syncs is determined by the application; however, enough time must be provided so that the host can execute the required number of software instructions in the time between the end of the primary data transfer (rising edge of the primary frame-sync interval) and the falling edge of the secondary frame sync (start of secondary communications).

Figure 2–3. Slave and Codec Functional Sequence

2.17 Request for Secondary Serial Communication and Phase Shift

The following paragraphs describe a request for secondary serial communication and phase shift using hardware control inputs FC1 and FC0, primary data bits D01 and D00, and secondary data bits DS15 and DS14.

2.17.1 Initiating a Request

Combinations of FC1 and FC0 input conditions, bits D01 and D00 in the primary serial data word, FC1 and FC0, and bits DS15 and DS14 in the secondary serial data word can be used to initiate a secondary serial communication or request a phase shift according to the following rules (see Table 2–3).

1. Primary word phase shifts can be requested by either the hardware or software if the other set of signals are 11 or 00. If both hardware and software request phase shifts, the software request is performed.
2. Secondary words can be requested by either the software or hardware at the same time that the other set of signals is requesting a phase shift.
3. Hardware inputs FC1 and FC0 are ignored during the secondary word unless DS15 and DS14 are 11. If DS15 and DS14 are 01 or 10, the corresponding phase shift is performed. If DS15 and DS14 are 00, no phase shift is performed even if the hardware requests a phase shift.

2.17.2 Normal Combinations of Control

The normal combinations of control are as follows:

1. Use D01 and D00 and DS15 and DS14 to request phase shifts and secondary words by holding FC1 and FC0 to 00
2. Use FC1 and FC0 exclusively to request phase shifts and secondary words by holding D01 and D00 to 00 and DS15 and DS14 to 11
3. Use D01 and D00 only to request secondary words and FC1 and FC0 to perform phase shifts once per period by holding DS15 and DS14 to 00

2.17.3 Additional Control Options

Additional control options are unusual and rarely needed or used; however, they are as follows:

1. Use D01 and D00 only to request secondary words and FC1 and FC0 to perform phase shifts twice per period by holding DS15 and DS14 to 11
2. Use FC1 and FC0 exclusively to request secondary words and D01 and D00 and DS15 and DS14 to perform phase shifts twice per period
3. Use FC1 and FC0 to perform the phase shift after the primary word and DS15 and DS14 to perform a phase shift after the secondary word by holding D01 and D00 to 11

**Table 2–3. Software and Hardware Requests for
Secondary Serial-Communication and Phase-Shift Truth Table**

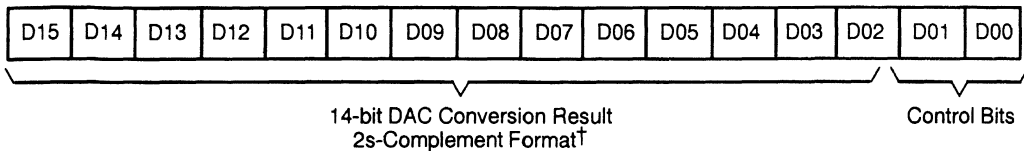
WITHIN PRIMARY OR SECONDARY DATA WORD	CONTROL BITS		HARDWARE TERMINALS		PHASE-SHIFT ADJUSTMENT (see Section 2.15.1)		SECONDARY REQUEST (see Note 1)
	D01	D00	FC1	FC0	EARLIER	LATER	
Primary	0	0	0	0	0	0	0
	0	0	0	1	0	1	0
	0	0	1	0	1	0	0
	0	0	1	1	0	0	1
	0	1	0	0	0	1	0
	0	1	0	1	0	1	0
	0	1	1	0	0	1	0
	0	1	1	1	0	1	1
	1	0	0	0	1	0	0
	1	0	0	1	1	0	0
	1	0	1	0	1	0	0
	1	0	1	1	1	0	1
	1	1	0	0	0	0	1
	1	1	0	1	0	1	1
	1	1	1	0	1	0	1
	1	1	1	1	0	0	1
Secondary	DS15	DS14	FC1	FC0	EARLIER	LATER	No request can be made for secondary communication within the secondary word.
	0	0	0	0	0	0	
	0	0	0	1	0	0	
	0	0	1	0	0	0	
	0	0	1	1	0	0	
	0	1	0	0	0	1	
	0	1	0	1	0	1	
	0	1	1	0	0	1	
	0	1	1	1	0	1	
	1	0	0	0	1	0	
	1	0	0	1	1	0	
	1	0	1	0	1	0	
	1	0	1	1	1	0	
	1	1	0	0	0	0	
	1	1	0	1	0	1	
	1	1	1	0	1	0	
1	1	1	1	0	0		

NOTE 1: The 0 state indicates that a secondary communication is not being requested. The 1 state indicates that a secondary communication is being requested.

2.18 Primary Serial Communications

Primary serial communications transfer the 14-bit DAC input plus two control bits (D01 and D00) to DIN of the TLC320AC02. They simultaneously transfer the 14-bit ADC conversion result from DOUT to the processor. The two LSBs are set to zero in the ADC result.

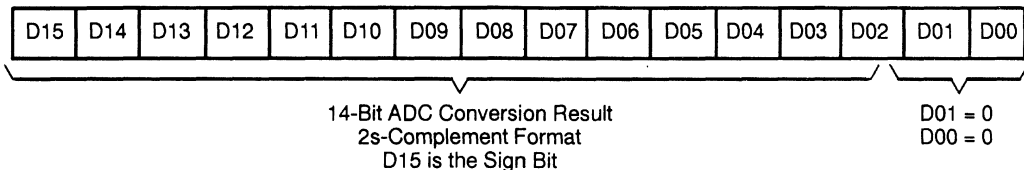
2.18.1 Primary Serial Communications Data Format



† Since the supply voltage is single ended, the reference for 2s-complement format is ADC V_{MID} . Voltages above this reference have a 0 as the MSB, and voltages below this reference have a 1 as the MSB.

During primary serial communications, if D01 and D00 are both high in the DAC data word to DIN, a subsequent 16 bits of control information is received by the device at DIN during a secondary serial-communication interval. This secondary serial-communication interval begins at 1/2 the programmed conversion time if the B register data value is even or 1/2 the programmed value minus one FCLK if the B register data value is odd. The time between primary and secondary serial communication is measured from the falling edge of the primary frame sync to the falling edge of the secondary frame sync (see Section 2.19, Secondary Serial Communications for function and format of control words).

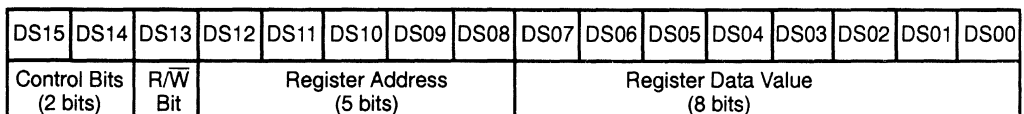
2.18.2 Data Format From DOUT During Primary Serial Communications



2.19 Secondary Serial Communications

2.19.1 Data Format to DIN During Secondary Serial Communications

There are nine 16-bit configuration and control registers numbered from zero to eight. All register data contents are represented in 2s-complement format. The general format of the commands during secondary serial communications is as follows.

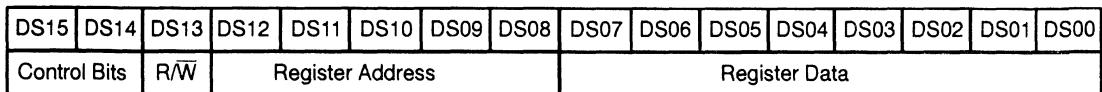


All control register words are latched in the register and valid on the 16th falling edge of SCLK.

2.19.2 Control Data-Bit Function in Secondary Serial Communication

2.19.2.1 DS15 and DS14

In the secondary data word, bits DS15 and DS14 perform the same control function as the primary control bits D01 and D00 do in the primary data word.



Hardware terminals FC1 and FC0 are valid inputs when DS15 and DS14 are both high, and they are ignored for all other conditions.

2.19.2.2 DS13 (R/W Bit)

Reset and power-up procedures set this bit to a zero, placing the device in the write mode. When this bit is set to one, however, the previous data content of the register being addressed is read out to the host from DOUT as the least significant eight bits of the 16-bit secondary word. The first eight bits remain set to zero. Reading the data out is nondestructive, and the contents of the register remain unchanged.

A. Write Mode (DS13 = 0)

Data In. The data word to DIN has the following general format in the write mode.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00	
Control Bits		0	Register Address					Register Data								

Data Out. The shift-clock shifts out all zeros as the pattern to the host from DOUT.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0

B. Read Mode (DS13 = 1)

Data In. The data word to DIN has the following format to allow a register read. Phase shifts can also be done in the read mode.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00	
Control Bits		1	Register Address					Ignored								

Data Out. The shift-clock clocks out the data of the register addressed from DOUT in the read mode in the eight LSBs.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0	Register Data							

2.20 Internal Register Format

2.20.1 Pseudo-Register 0 (No-Op Address)

This address represents a no-operation command. No register I/O operation takes place, so the device can receive secondary commands for phase adjustment without reprogramming any register. A read of the no-op is zero. The format of the command word is as follows.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		X	0	0	0	0	0	X	X	X	X	X	X	X	X

2.20.2 Register 1 (A Register)

The following command loads DS07 (MSB) – DS00 into the A register.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/W	0	0	0	0	1	Register Data							

The data in DS07 – DS00 determines the division of the master clock to produce the internal FCLK.

$$\text{FCLK frequency} = \text{MCLK}/(\text{A register contents} \times 2)$$

The default value of the A-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

2.20.3 Register 2 (B Register)

The following command loads DS07 (MSB) – DS00 into the B register.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	R/W	0	0	0	1	0	Register Data								

The data in DS07 – DS00 controls the division of FCLK to generate the conversion clock.

$$\begin{aligned} \text{Conversion frequency} &= \text{FCLK}/(\text{B register contents}) \\ &= \frac{\text{MCLK}}{2 \times \text{A register contents} \times \text{B register contents}} \end{aligned}$$

The default value of the B-register data is decimal 18 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	1	0	0	1	0

2.20.4 Register 3 (A' Register)

The following command contains the A'-register address and loads DS07(MSB) – DS00 into the A' register.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits	R/W	0	0	0	1	1	Register Data								

The data in DS07 – DS00 is in 2s-complement format and controls the number of master clock periods that the sampling time is shifted.

The default value of the A'-register data is 0 as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

2.20.5 Register 4 (Amplifier Gain-Select Register)

The following command contains the amplifier gain-select register address with selection code for the monitor output (DS05–DS04), analog input (DS03–DS02), and analog output (DS01–DS00) programmable gains.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00	
Control Bits	R/W	0	0	1	0	0	X	X	X	*	*	*	*	*	*	
Monitor output gain = squelch	→										0	0				
Monitor output gain = 0 dB	→										0	1				
Monitor output gain = -8 dB	→										1	0				
Monitor output gain = -18 dB	→										1	1				
Analog input gain = squelch	→												0	0		
Analog input gain = 0 dB	→												0	1		
Analog input gain = 6 dB	→												1	0		
Analog input gain = 12 dB	→												1	1		
Analog output gain = squelch	→														0	0
Analog output gain = 0 dB	→														0	1
Analog output gain = -6 dB	→														1	0
Analog output gain = -12 dB	→														1	1

The default value of the monitor output gain is squelch, which corresponds to data bits DS05 and DS04 equal to 00 (binary).

The default value of the analog input gain is 0 dB, which corresponds to data bits DS03 and DS02 equal to 01 (binary).

The default value of the analog output gain is 0 dB, which corresponds to data bits DS01 and DS00 equal to 01 (binary).

The default data value is shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	1	0	1

2.20.6 Register 5 (Analog Configuration Register)

The following command is used to load the analog configuration register with the individual bit functions described below.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00	
Control Bits	R/W	0	0	1	0	1	X	X	X	X	*	*	*	*		
Must be set to 0	→										0					
High-pass filter disabled	→												1			
High-pass filter enabled	→												0			
Analog loopback enabled	→														0	0
Enables IN+ and IN- (disables AUXIN+ and AUXIN-)	→														0	1
Enables AUXIN+ and AUXIN- (disables IN+ and IN-)	→														1	0
Enable analog input summing	→														1	1

The default value of the high-pass-filter enable bit is zero, which places the high-pass filter in the signal path. The default values of DS01 and DS00 are zero and one, which enables IN+ and IN-.

The power-up and reset conditions are as shown below.

DS03	DS02	DS01	DS00
0	0	0	1

In the read mode, eight bits are read but the four LSBs are repeated as the four MSBs.

2.20.7 Register 6 (Digital Configuration Register)

The following command is used to load the digital configuration register with the individual bit functions described below.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/W	0	0	1	1	0	X	X	*	*	*	*	*	*
ADC and DAC conversion free run										1					
Inactive										0					
FSD output disable										1					
Enable										0					
16-Bit mode, ignore primary LSBs											1				
Normal operation											0				
Force secondary communications												1			
Normal operation												0			
Software reset													1		
(upon reset, this bit is automatically reset to 0)															
Inactive reset													0		
Software power-down active (automatically reset to 0 after PWR DWN is cycled high to low and back to high)															1
Power-down function external (uses PWR DWN)															0

The default value of DS07–DS00 is zero, as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

2.20.8 Register 7 (Frame-Sync Delay Register)

The following command contains the frame-sync delay (FSD) register address and loads DS07 (MSB)–DS00 into the FSD register. The data byte (DS01–DS00) determines the number of SCLKs between \overline{FS} and the delayed frame-sync signal, \overline{FSD} . The minimum data value for this register is decimal 18.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/W	0	0	1	1	1	Register Data							

The default value of DS07 – DS00 is zero, as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	0

When using a slave device, register 7 must be the last register programmed.

2.20.9 Register 8 (Frame-Sync Number Register)

The following command contains the frame-sync number (FSN) register address and loads DS07 (MSB)–DS00 into the FSN register. The data byte determines the number of frame-sync signals generated by the TLC320AC02.

DS15	DS14	DS13	DS12	DS11	DS10	DS09	DS08	DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
Control Bits		R/ \overline{W}	0	1	0	0	0	Register Data							

The default value of DS07–DS00 is one, as shown below.

DS07	DS06	DS05	DS04	DS03	DS02	DS01	DS00
0	0	0	0	0	0	0	1

3 Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (Unless Otherwise Noted)[†]

Supply voltage range, DGTL V_{DD} (see Notes 1 and 2)	-0.3 V to 6.5 V
Supply voltage range, DAC V_{DD} (see Notes 1 and 2)	-0.3 V to 6.5 V
Supply voltage range, ADC V_{DD} (see Notes 1 and 2)	-0.3 V to 6.5 V
Differential supply voltage range, DGTL V_{DD} to DAC V_{DD}	-0.3 V to 6.5 V
Differential supply voltage range, all positive supply voltages to ADC GND, DAC GND, DGTL GND, SUBS	-0.3 V to 6.5 V
Output voltage range, DOUT	-0.3 V to DGTL V_{DD} + 0.3 V
Input voltage range, DIN	-0.3 V to DGTL V_{DD} + 0.3 V
Ground voltage range, ADC GND, DAC GND, DGTL GND, SUBS	-0.3 V to DGTL V_{DD} + 0.3 V
Operating free-air temperature range: TLC320AC02C	0°C to 70°C
TLC320AC02I	-40°C to 85°C
Storage temperature range	-40°C to 125°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

3.2 Recommended Operating Conditions (see Note 2)

		MIN	NOM	MAX	UNIT
V_{DD}	Positive supply voltage	4.5	5	5.5	V
	Steady-state differential voltage between any two supplies			0.1	V
V_{IH}	High-level digital input voltage	2.2			V
V_{IL}	Low-level digital input voltage			0.8	V
I_O	Load current from ADC V_{MID} and DAC			100	μ A
	Conversion time for the ADC and DAC channels		10 FCLK periods		
f_{MCLK}	Master clock frequency		10.368	15	MHz
$V_{ID(PP)}$	Analog input voltage (differential, peak to peak)		6		V
R_L	Differential output load resistance	600			Ω
	Single-ended to buffered DAC V_{MID} voltage load resistance	300			
T_A	Operating free-air temperature	TLC320AC02C	0	70	$^{\circ}$ C
		TLC320AC02I	-40	85	

- NOTES: 1. Voltage values for DGTL V_{DD} are with respect to DGTL GND, voltage values for DAC V_{DD} are with respect to DAC GND, and voltage values for ADC V_{DD} are with respect to ADC GND. For the subsequent electrical, operating, and timing specifications, the symbol V_{DD} is used to denote all positive supplies. DAC GND, ADC GND, DGTL GND, and SUBS are at 0 V unless otherwise specified.
2. To avoid possible damage to these CMOS devices and associated operating parameters, the sequence below should be followed when applying power:
- (1) Connect SUBS, DGTL GND, ADC GND, and DAC GND to ground.
 - (2) Connect voltages ADC V_{DD} , and DAC V_{DD} .
 - (3) Connect voltage DGTL V_{DD} .
 - (4) Connect the input signals.
- When removing power, follow the steps above in reverse order.

3.3 Electrical Characteristics Over Recommended Range of Operating Free-Air Temperature, MCLK = 5.184 MHz, V_{DD} = 5 V, Outputs Unloaded, Total Device

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
I _{DD} Supply current	PWR DWN = 1 and clock signals present		20	22	mA
	PWR DWN = 0 after 500 μs and clock signals present		1	2	mA
P _D Power dissipation	PWR DWN = 1 and clock signals present		100		mW
	PWR DWN = 0 after 500 μs and clock signals present		5		mW
	Software power down, (bit D00, register 6 set to 1)		15	20	mW
ADC V _{MID}	No load	ADC V _{DD} /2 - 0.1		ADC V _{DD} /2 + 0.1	V
DAC V _{MID}	No load	DAC V _{DD} /2 - 0.1		DAC V _{DD} /2 + 0.1	V

3.4 Electrical Characteristics Over Recommended Range of Operating Free-Air Temperature, V_{DD} = 5 V, Digital I/O Terminals (DIN, DOUT, EOC, FC0, FC1, FS, FSD, MCLK, M/S, SCLK)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V _{OH} High-level output voltage	I _{OH} = -1.6 mA		2.4		V
V _{OL} Low-level output voltage	I _{OL} = 1.6 mA			0.4	V
I _{IH} High-level input current, any digital input	V _I = 2.2 V to DGTL V _{DD}			10	μA
I _{IL} Low-level input current, any digital input	V _I = 0 V to 0.8 V			10	μA
C _i Input capacitance				5	pF
C _o Output capacitance				5	pF

† All typical values are at V_{DD} = 5 V and T_A = 25°C.

3.5 Electrical Characteristics Over Recommended Range of Operating Free-Air Temperature, V_{DD} = 5 V, ADC and DAC Channels

3.5.1 ADC Channel Filter Transfer Function, FCLK = 144 kHz, f_s = 8 kHz

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Gain relative to gain at f _i = 1020 Hz (see Note 3)	f _i = 50 Hz		-2	dB
	f _i = 200 Hz	-1.8	-0.2	
	f _i = 300 Hz to 3 kHz	-0.2	0.2	
	f _i = 3.3 kHz	-0.35	0.03	
	f _i = 3.4 kHz	-1	-0.1	
	f _i = 4 kHz		-14	
	f _i ≥ 4.6 kHz		-32	

NOTE 3: The differential analog input signals are sine waves at 6 V peak to peak. The reference gain is at 1020 Hz.

3.5.2 ADC Channel Input, $V_{DD} = 5\text{ V}$, Input Amplifier Gain = 0 dB (Unless Otherwise Noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{I(PP)}$	Peak-to-peak input voltage (see Note 4)	Single ended		3		V
		Differential		6		V
ADC converter offset error		Band-pass filter selected		10	30	mV
CMRR	Common-mode rejection ratio at IN+, IN-, AUX IN+, AUX IN- (see Note 5)			55		dB
r_i	Input resistance at IN+, IN-, AUX IN+, AUX IN-			100		k Ω
Squelch		DS03, DS02 = 0 in register 4		60		dB

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 4. The differential range corresponds to the full-scale digital output.

5. Common-mode rejection ratio is the ratio of the ADC converter offset error with no signal and the ADC converter offset error with a common-mode nonzero signal applied to either IN+ and IN- together or AUX IN+ and AUX IN- together.

3.5.3 ADC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = 6\text{ dB}$		$A_V = 12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
ADC channel signal-to-distortion ratio (see Note 6)	$V_I = -6\text{ dB to } -1\text{ dB}$	64		—		—		dB
	$V_I = -12\text{ dB to } -6\text{ dB}$	59		64		—		
	$V_I = -18\text{ dB to } -12\text{ dB}$	56		59		64		
	$V_I = -24\text{ dB to } -18\text{ dB}$	50		56		59		
	$V_I = -30\text{ dB to } -24\text{ dB}$	44		50		56		
	$V_I = -36\text{ dB to } -30\text{ dB}$	38		44		50		
	$V_I = -42\text{ dB to } -36\text{ dB}$	32		38		44		
$V_I = -48\text{ dB to } -42\text{ dB}$	26		32		38			

NOTE 6: The analog input test signal is a 1020-Hz sine wave with 0 dB = 6 V peak to peak as the reference level for the analog input signal.

3.5.4 DAC Channel Filter Transfer Function, $F_{CLK} = 144\text{ kHz}$, $f_s = 9.6\text{ kHz}$, $V_{DD} = 5\text{ V}$

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
Gain relative to gain at $f_i = 1020\text{ Hz}$ (see Note 7)	$f_i < 200\text{ Hz}$		0.15	dB
	$f_i = 200\text{ Hz}$	-0.5	0.2	
	$f_i = 300\text{ Hz to } 3\text{ kHz}$	-0.2	0.2	
	$f_i = 3.3\text{ kHz}$	-0.35	0.03	
	$f_i = 3.4\text{ kHz}$	-1	-0.1	
	$f_i = 4\text{ kHz}$		-14	
	$f_i \geq 4.6\text{ kHz}$		-32	

NOTE 7: The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak.

3.5.5 DAC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = -6\text{ dB}$		$A_V = -12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
DAC channel signal-to-distortion ratio (see Note 8)	$V_O = -6\text{ dB to }0\text{ dB}$	64	—	—	—	—	—	dB
	$V_O = -12\text{ dB to }-6\text{ dB}$	59	—	64	—	—	—	
	$V_O = -18\text{ dB to }-12\text{ dB}$	56	—	59	—	64	—	
	$V_O = -24\text{ dB to }-18\text{ dB}$	50	—	56	—	59	—	
	$V_O = -30\text{ dB to }-24\text{ dB}$	44	—	50	—	56	—	
	$V_O = -36\text{ dB to }-30\text{ dB}$	38	—	44	—	50	—	
	$V_O = -42\text{ dB to }-36\text{ dB}$	32	—	38	—	44	—	
$V_O = -48\text{ dB to }-42\text{ dB}$	26	—	32	—	38	—		

NOTE 8: The input signal, V_I , is the digital equivalent of a 1020-Hz sine wave (full-scale analog output at full-scale digital input = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT + to OUT –.

3.5.6 System Distortion, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$, FCLK = 144 kHz (Unless Otherwise Noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC channel attenuation	Second harmonic	Single-ended input (see Note 9)	82			dB
		Differential input (see Note 9)	64	82		
	Third harmonic and higher harmonics	Single-ended input (see Note 9)	77			
		Differential input (see Note 9)	64	77		
DAC channel attenuation	Second harmonic	Single-ended output (buffered DAC V_{MID}) (see Note 10)	82			
		Differential output (see Note 10)	64	82		
	Third harmonic and higher harmonics	Single-ended output (see Note 10)	77			
		Differential output (see Note 10)	64	77		

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 9. The input signal is a 1020-Hz sine wave for the ADC channel. Harmonic distortion is defined for an input level of –1 dB.

10. The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT + to OUT –. Harmonic distortion is specified for a signal input level of 0 dB.

3.5.7 Noise, Low-Pass and Band-Pass Switched-Capacitor Filters Included, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted)

PARAMETER		TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC idle channel noise		Inputs tied to ADC V_{MID} $f_s = 8\text{ kHz}$, $FCLK = 144\text{ kHz}$, (see Note 11)		180	300	μV_{rms}
DAC idle channel noise	Broad-band noise	DIN INPUT = 000000000000000		180	300	
	Noise (0 to 7.2 kHz)	$f_s = 8\text{ kHz}$, $FCLK = 144\text{ kHz}$, (see Note 12)		180	300	
	Noise (0 to 3.6 kHz)			180	300	

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 11. The ADC channel noise is calculated by taking the RMS value of the digital output codes of the ADC channel and converting to microvolts.

12. The DAC channel noise is measured differentially from $OUT+$ to $OUT-$ across $600\ \Omega$.

3.5.8 Absolute Gain Error, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS		MIN	MAX	UNIT
ADC channel absolute gain error (see Note 13)	-1-dB input signal	$T_A = -40\text{ to }85^\circ\text{C}$		± 1	dB
DAC channel absolute gain error (see Note 14)	0-dB input signal, $R_L = 600\ \Omega$	$T_A = -40\text{ to }85^\circ\text{C}$		± 1	

NOTES: 13. ADC absolute gain error is the variation in gain from the ideal gain over the specified input signal levels. The gain is measured with a -1-dB, 1020-Hz sine wave. The -1-dB input signal allows for any positive gain or offset error that may affect gain measurements at or close to 0-dB input signal levels.

14. The DAC input signal is the digital equivalent of a 1020-Hz sine wave (full-scale analog output at digital full-scale input = 0 dB). The nominal differential DAC channel output voltage with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is $600\ \Omega$ from $OUT+$ to $OUT-$.

3.5.9 Relative Gain and Dynamic Range, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	MIN	MAX	UNIT
ADC channel relative gain tracking error (see Note 15)	-48-dB to -1-dB input signal range		± 0.2	dB
DAC channel relative gain tracking error (see Note 16)	-48-dB to 0-dB input signal range $R_L(\text{diff}) = 600\ \Omega$		± 0.2	

NOTES: 15. ADC gain tracking is the ratio of the measured gain at one ADC channel input level to the gain measured at any other input level. The ADC channel input is a -1-dB 1020-Hz sine wave input signal. A -1-dB input signal allows for any positive gain or offset error that may affect gain measurements at or close to 0-dB ADC input signal levels.

16. DAC gain tracking is the ratio of the measured gain at one DAC channel digital input level to the gain measured at any other input level. The DAC channel input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output voltage with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is $600\ \Omega$ from $OUT+$ to $OUT-$.

3.5.10 Power-Supply Rejection, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted)(see Note 17)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC V_{DD} Supply-voltage rejection ratio, ADC channel	$f_i = 0$ to 30 kHz		50		dB
	$f_i = 30$ to 50 kHz		55		
DAC V_{DD} Supply-voltage rejection ratio, DAC channel	$f_i = 0$ to 30 kHz		40		
	$f_i = 30$ to 50 kHz		45		
DGTL V_{DD} Supply-voltage rejection ratio, ADC channel	$f_i = 0$ to 30 kHz		50		
	$f_i = 30$ to 50 kHz		55		
DGTL V_{DD} Supply-voltage rejection ratio, DAC channel	Single ended, $f_i = 0$ to 30 kHz		40		
	$f_i = 30$ to 50 kHz		45		
	Differential, $f_i = 0$ to 30 kHz		40		
	$f_i = 30$ to 50 kHz		45		

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTE 17: Power-supply rejection measurements are made with both the ADC and the DAC channels idle and a 200-mV peak-to-peak signal applied to the appropriate supply.

3.5.11 Crosstalk Attenuation, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
ADC channel crosstalk attenuation	DAC channel idle with DIN = 0000000000000000, ADC input = 0 dB, 1020-Hz sine wave, Gain = 0 dB (see Note 18)		80		dB
DAC channel crosstalk attenuation	ADC channel idle with INP, INM, AUX IN+, and AUX IN- at ADC V_{MID}		80		dB
	DAC channel input = digital equivalent of a 1020-Hz sine wave (see Note 19)		80		

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 18. The test signal is a 1020-Hz sine wave with a 0 dB = 6-V peak-to-peak reference level for the analog input signal.

19. The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT+ to OUT-.

3.5.12 Monitor Output Characteristics, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 20)

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
$V_{O(PP)}$ Peak-to-peak ac output voltage	Quiescent level = ADC V_{MID} $Z_L = 10\text{ k}\Omega$ and 60 pF	1.3	1.5		V
V_{OO} Output offset voltage	No load, single ended relative to ADC V_{MID}		5	10	mV
r_o DC output resistance			50		Ω
V_{OC} Output common-mode voltage	No load	0.4 ADC V_{DD}	0.5 ADC V_{DD}	0.6 ADC V_{DD}	V
A_V Voltage gain (see Note 21)	Gain = 0 dB	-0.2	0	0.2	dB
	Gain 2 = -8 dB	-8.2	-8	-7.8	
	Gain 3 = -18 dB	-18.4	-18	-17.6	
	Squelch (see Note 22)			-60	

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 20. All monitor output tests are performed with a $10\text{-k}\Omega$ load resistance.

21. Monitor gains are measured with a 1020-Hz , 6-V peak-to-peak sine wave applied differentially between $IN+$ and $IN-$. The monitor output gains are nominally 0 dB , -8 dB , and -18 dB relative to its input; however, the output gains are -6 dB relative to $IN+$ and $IN-$ or $AUX\ IN+$ and $AUX\ IN-$.

22. Squelch is measured differentially with respect to ADC V_{MID} .

3.6 Timing Requirements and Specifications in Master Mode

3.6.1 Recommended Input Timing Requirements for Master Mode, $V_{DD} = 5\text{ V}$

		MIN	NOM	MAX	UNIT
$t_r(\text{MCLK})$	Master clock rise time		5		ns
$t_f(\text{MCLK})$	Master clock fall time		5		ns
	Master clock duty cycle	40%		60%	
$t_w(\text{RESET})$	RESET pulse duration	1 MCLK			
$t_{su}(\text{DIN})$	DIN setup time before SCLK low (see Figure 4-2)	25			ns
$t_h(\text{DIN})$	DIN hold time after SCLK high (see Figure 4-2)			20	ns

3.6.2 Operating Characteristics Over Recommended Range of Operating Free-Air Temperature, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 23)

PARAMETER		MIN	TYP†	MAX	UNIT
$t_f(\text{SCLK})$	Shift clock fall time (see Figure 4-2)		13	18	ns
$t_r(\text{SCLK})$	Shift clock rise time (see Figure 4-2)		13	18	ns
	Shift clock duty cycle	45%		55%	
$t_d(\text{CH-FL})$	Delay time from SCLK high to $\overline{\text{FSD}}$ low (see Figures 4-2 and 4-4 and Note 24)		5	20	ns
$t_d(\text{CH-FH})$	Delay time from SCLK high to $\overline{\text{FS}}$ high (see Figure 4-2)		5	20	ns
$t_d(\text{CH-DOUT})$	Delay time from SCLK high to DOUT valid (see Figures 4-2 and 4-7)			20	ns
$t_d(\text{CH-DOUTZ})$	Delay time from SCLK↑ to DOUT in high-impedance state (see Figure 4-8)		20		ns
$t_d(\text{ML-EL})$	Delay time from MCLK low to EOC low (see Figure 4-9)		40		ns
$t_d(\text{ML-EH})$	Delay time from MCLK low to EOC high (see Figure 4-9)		40		ns
$t_f(\text{EL})$	EOC fall time (see Figure 4-9)		13		ns
$t_r(\text{EH})$	EOC rise time (see Figure 4-9)		13		ns
$t_d(\text{MH-CH})$	Delay time from MCLK high to SCLK high			50	ns
$t_d(\text{MH-CL})$	Delay time from MCLK high to SCLK low			50	ns

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTES: 23. All timing specifications are valid with $C_L = 20\text{ pF}$.

24. $\overline{\text{FSD}}$ occurs 1/2 shift-clock cycle ahead of $\overline{\text{FS}}$ when the device is operating in the master mode.

3.7 Timing Requirements and Specifications in Slave Mode and Codec Emulation Mode

3.7.1 Recommended Input Timing Requirements for Slave Mode, $V_{DD} = 5\text{ V}$

		MIN	NOM	MAX	UNIT
$t_r(\text{MCLK})$	Master clock rise time		5		ns
$t_f(\text{MCLK})$	Master clock fall time		5		ns
	Master clock duty cycle	40%		60%	
$t_w(\text{RESET})$	$\overline{\text{RESET}}$ pulse duration	1 MCLK			
$t_{su}(\text{DIN})$	DIN setup time before SCLK low (see Figure 4-3)	20			ns
$t_h(\text{DIN})$	DIN hold time after SCLK high (see Figure 4-3)			20	ns
$t_{su}(\text{FL-CH})$	Setup time from $\overline{\text{FS}}$ low to SCLK high			$\pm \text{SCLK}/4$	ns

3.7.2 Operating Characteristics Over Recommended Range of Operating Free-Air Temperature, $V_{DD} = 5\text{ V}$ (Unless Otherwise Noted) (see Note 23)

PARAMETER		MIN	TYP†	MAX	UNIT
$t_c(\text{SCLK})$	Shift clock cycle time (see Figure 4-3)	125			ns
$t_f(\text{SCLK})$	Shift clock fall time (see Figure 4-3)			18	ns
$t_r(\text{SCLK})$	Shift clock rise time (see Figure 4-3)			18	ns
	Shift clock duty cycle	45%		55%	
$t_d(\text{CH-FDL})$	Delay time from SCLK high to $\overline{\text{FSD}}$ low (see Figure 4-6)			50	ns
$t_d(\text{CH-FDH})$	Delay time from SCLK high to $\overline{\text{FSD}}$ high			40	ns
$t_d(\text{FL-FDL})$	Delay time from $\overline{\text{FS}}$ low to $\overline{\text{FSD}}$ low (slave to slave) (see Figure 4-5)			40	ns
$t_d(\text{CH-DOU})$	Delay time from SCLK high to DOUT valid (see Figures 4-3 and 4-7)			40	ns
$t_d(\text{CH-DOU}T_Z)$	Delay time from SCLK↑ to DOUT in high-impedance state (see Figure 4-8)		20		ns
$t_d(\text{ML-EL})$	Delay time from MCLK low to EOC low (see Figure 4-9)		40		ns
$t_d(\text{ML-EH})$	Delay time from MCLK low to EOC high (see Figure 4-9)		40		ns
$t_f(\text{EL})$	EOC fall time (see Figure 4-9)		13		ns
$t_r(\text{EH})$	EOC rise time (see Figure 4-9)		13		ns
$t_d(\text{MH-CH})$	Delay time from MCLK high to SCLK high			50	ns
$t_d(\text{MH-CL})$	Delay time from MCLK high to SCLK low			50	ns

† All typical values are at $V_{DD} = 5\text{ V}$ and $T_A = 25^\circ\text{C}$.

NOTE 23: All timing specifications are valid with $C_L = 20\text{ pF}$.

4 Parameter Measurement Information

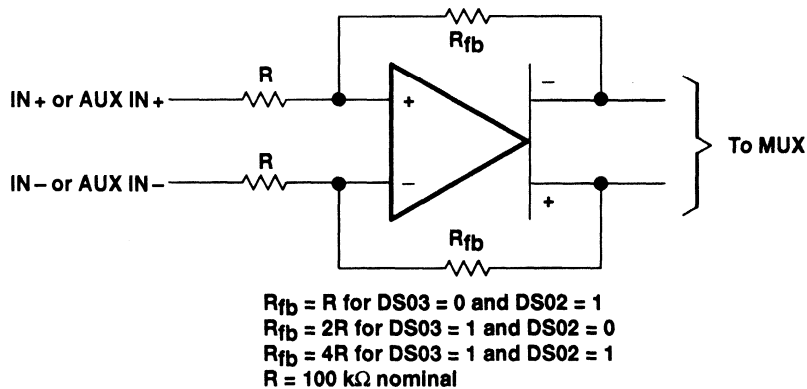


Figure 4-1. IN+ and IN- Gain-Control Circuitry

Table 4-1. Gain Control (Analog Input Signal Required for Full-Scale Bipolar A/D Conversion 2s Complement)†

INPUT CONFIGURATION	CONTROL REGISTER 4		ANALOG INPUT‡	A/D CONVERSION RESULT
	DS03	DS02		
Differential configuration Analog input = IN+ - IN- = AUX IN+ - AUX IN-	0	0	All	Squelch
	0	1	$V_{ID} = \pm 3 \text{ V}$	\pm Full scale
	1	0	$V_{ID} = \pm 1.5 \text{ V}$	\pm Full scale
	1	1	$V_{ID} = \pm 0.75 \text{ V}$	\pm Full scale
Single-ended configuration§ Analog input = IN+ - V_{MID} = AUX IN+ - V_{MID}	0	0	All	Squelch
	0	1	$V_I = \pm 1.5 \text{ V}$	\pm Half scale
	1	0	$V_I = \pm 1.5 \text{ V}$	\pm Full scale
	1	1	$V_I = \pm 0.75 \text{ V}$	\pm Full scale

† $V_{DD} = 5 \text{ V}$

‡ V_{ID} = differential input voltage, V_I = input voltage referenced to ADC V_{MID} with IN- or AUX IN- connected to ADC V_{MID} . In order to minimize distortion, it is recommended that the analog input not exceed 0.1 dB below full scale.

§ For single-ended inputs, the analog input voltage should not exceed the supply rails. All single-ended inputs should be referenced to the internal reference voltage, ADC V_{MID} , for best common-mode performance.

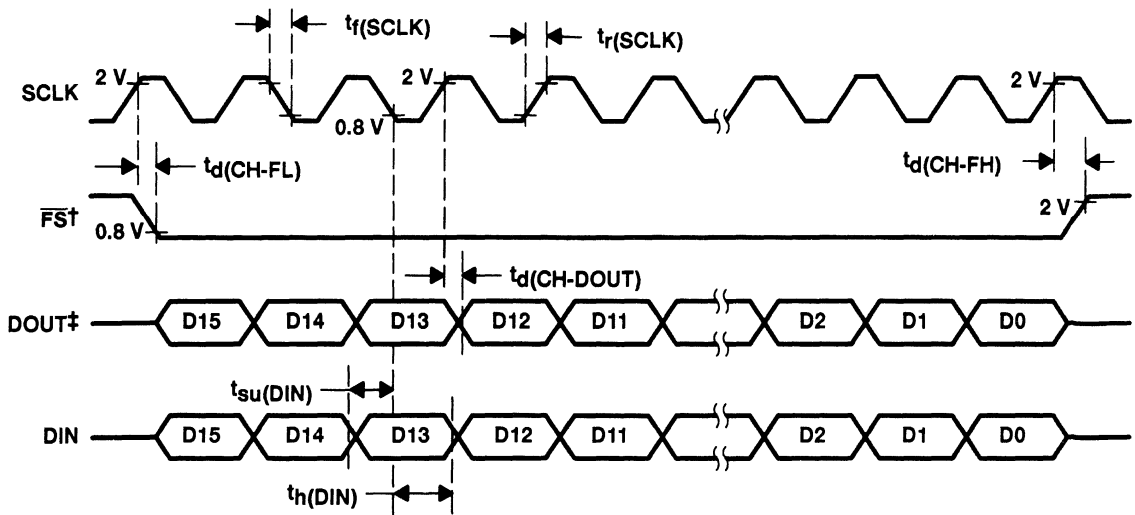


Figure 4–2. AIC Stand-Alone and Master-Mode Timing

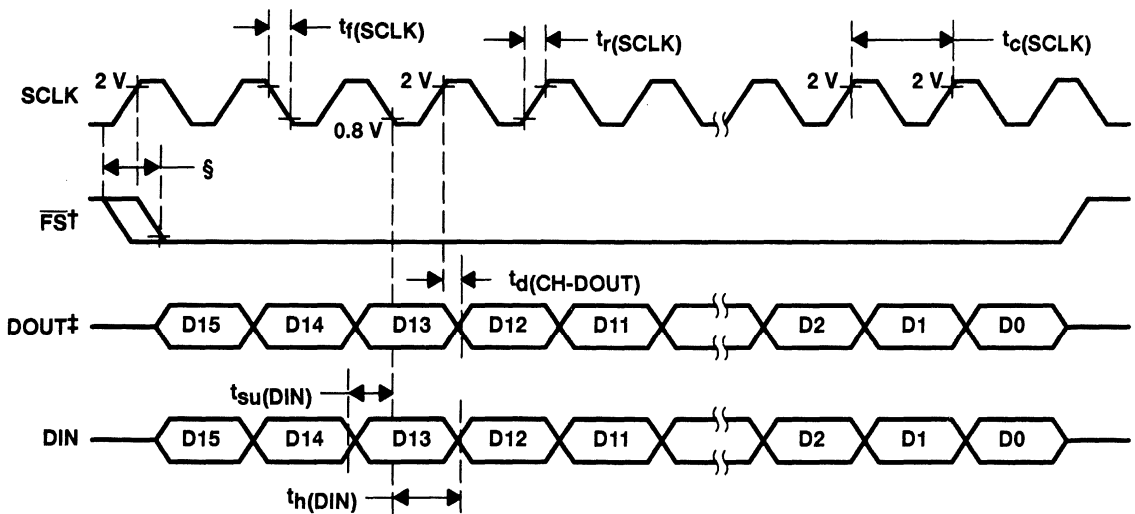
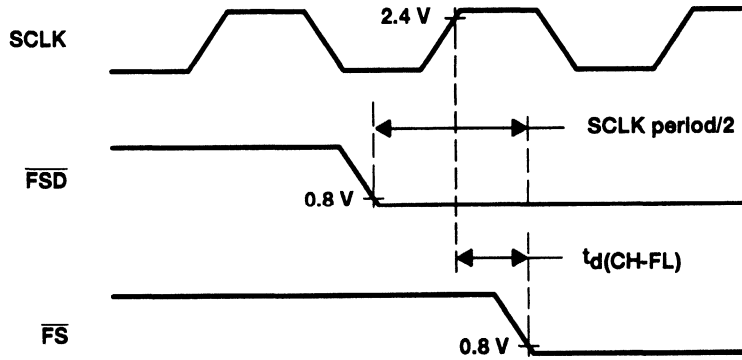


Figure 4–3. AIC Slave and Codec Emulation Mode

† The time between falling edges of two primary \overline{FS} signals is the conversion period.

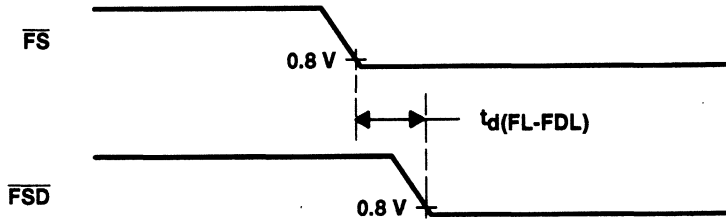
‡ The data on DOUT are shifted out on the rising edge of the shift clock, and the data on DIN are shifted in on the falling edge of the shift clock.

§ The high-to-low transition of \overline{FS} must occur within $\pm 1/4$ of a shift-clock period around the 2-V level of the shift clock.



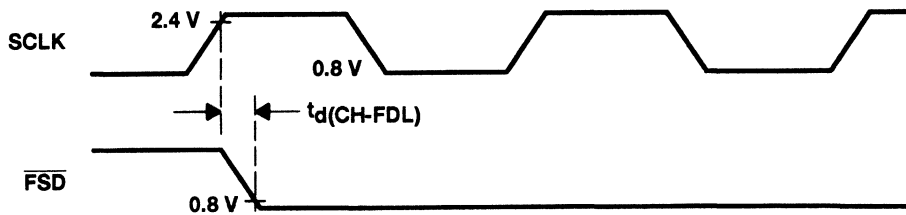
NOTE: Timing shown is for the TLC320AC02 operating as the master or as a stand-alone device.

Figure 4-4. Master or Stand-Alone \overline{FS} and \overline{FSD} Timing



NOTE: Timing shown is for the TLC320AC02 operating in the slave mode (\overline{FS} and SCLK signals generated externally). The programmed data value in the FSD register is 0.

Figure 4-5. Slave \overline{FS} to \overline{FSD} Timing



NOTE: Timing shown is for the TLC320AC02 operating in the slave mode (\overline{FS} and SCLK signals generated externally). There is a data value in the FSD register greater than 18 decimal.

Figure 4-6. Slave SCLK to \overline{FSD} Timing

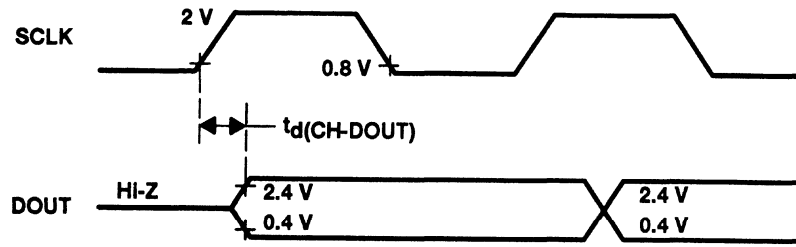


Figure 4–7. DOUT Enable Timing from Hi-Z

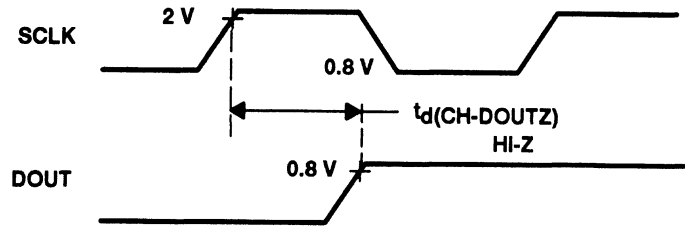


Figure 4–8. DOUT Delay Timing to Hi-Z

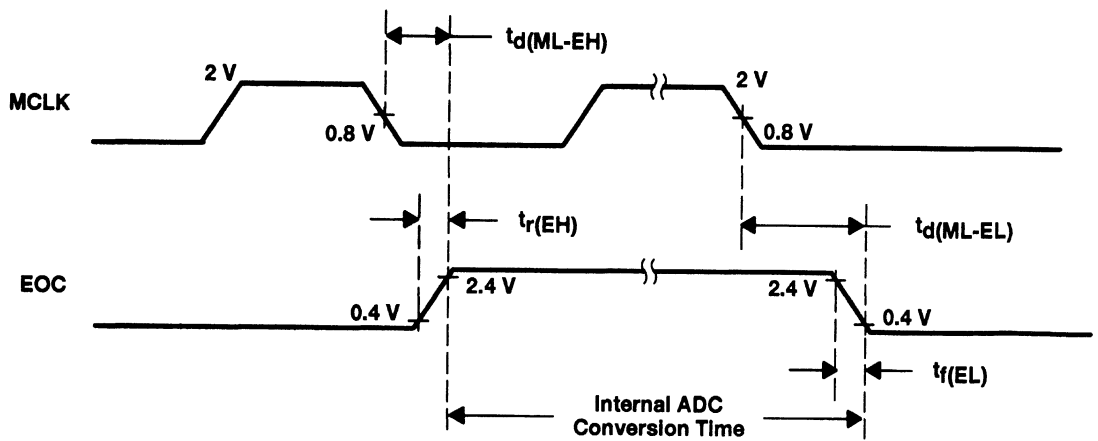
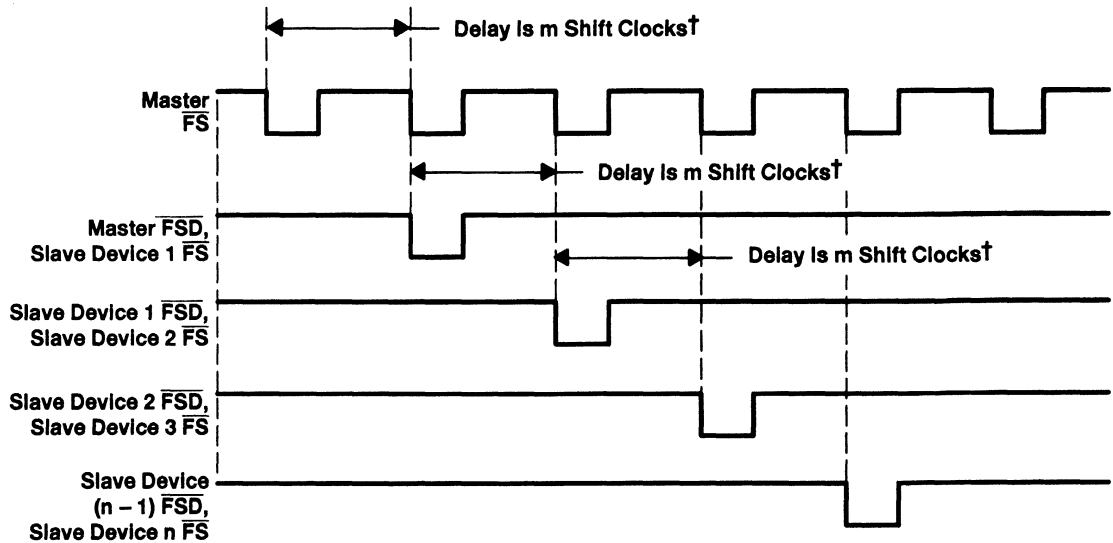


Figure 4–9. EOC Frame Timing



† The delay time from any \overline{FS} signals to the corresponding \overline{FSD} signals is m shift clocks with the value of m being the numerical value of the data programmed into the FSD register. In the master mode with slaves, the same data word is used to program the master and all slave devices; therefore, master to slave 1, slave 1 to slave 2, slave 2 to slave 3, etc., have the same delay time.

Figure 4–10. Master-Slave Frame-Sync Timing After a Delay Has Been Programmed into the FSD Registers

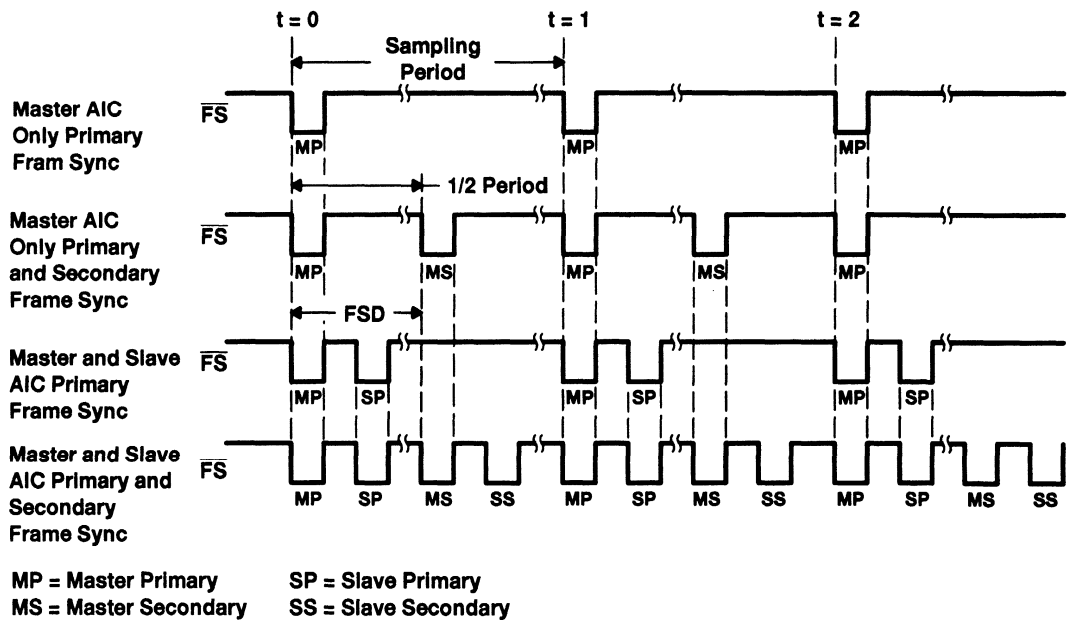


Figure 4–11. Master and Slave Frame-Sync Sequence with One Slave

5 Typical Characteristics

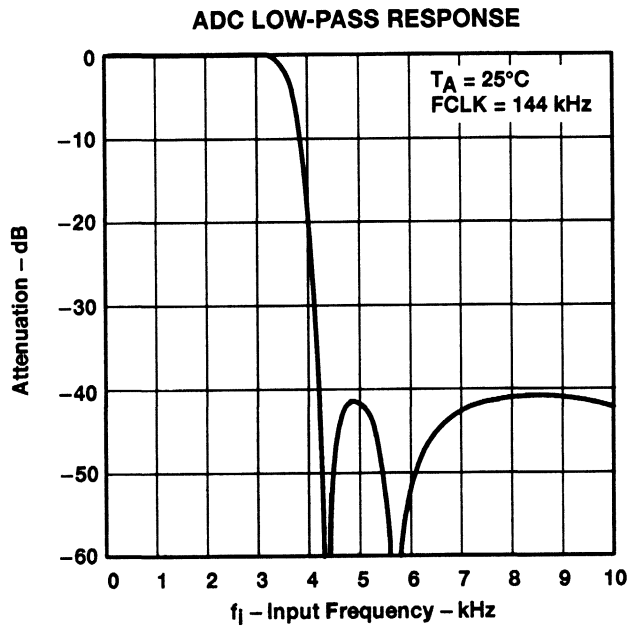


Figure 5-1

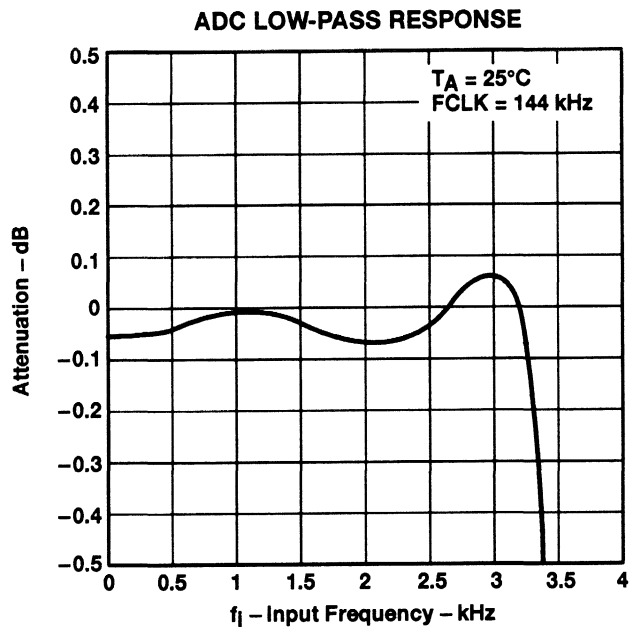


Figure 5-2

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{144}$

ADC GROUP DELAY

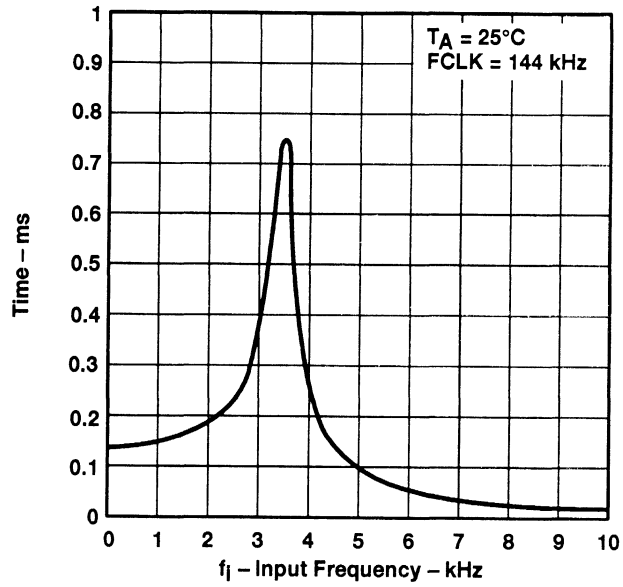


Figure 5-3

ADC BAND-PASS RESPONSE

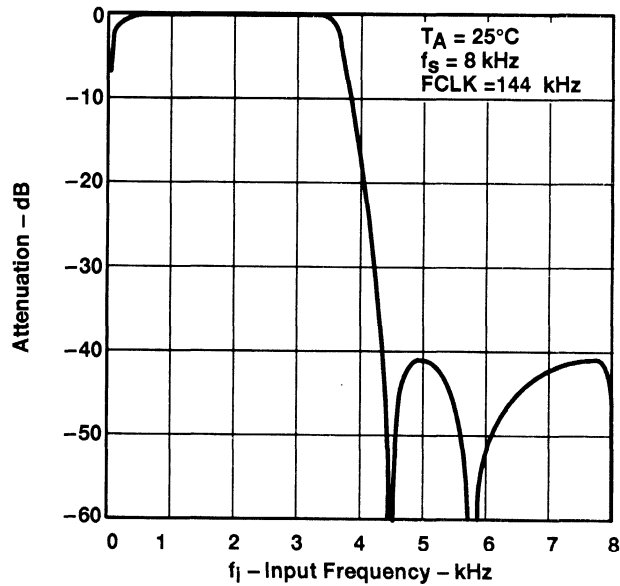


Figure 5-4

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times FCLK\text{ (kHz)}}{144}$

ADC BAND-PASS RESPONSE

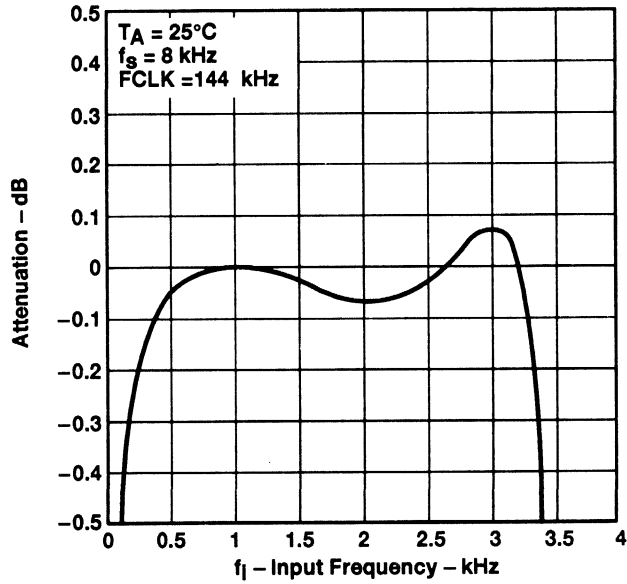


Figure 5-5

ADC HIGH-PASS RESPONSE

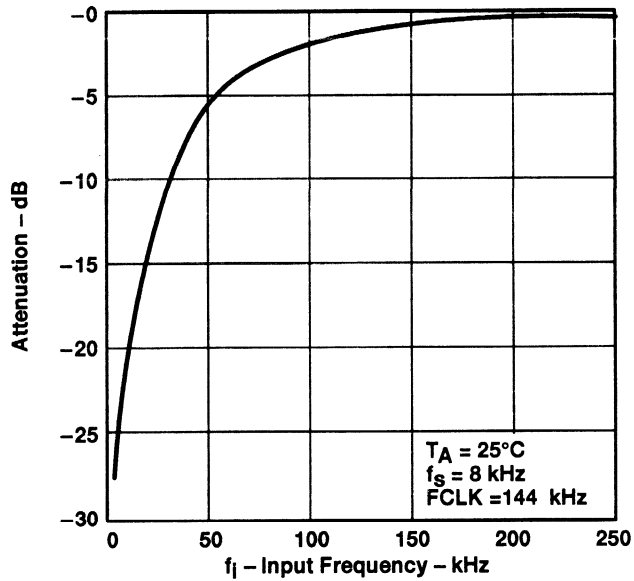


Figure 5-6

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times FCLK \text{ (kHz)}}{144}$

ADC BAND-PASS GROUP DELAY

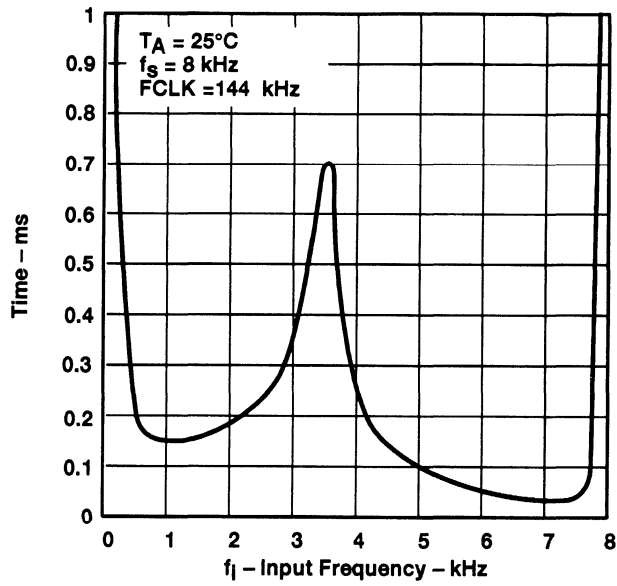


Figure 5-7

DAC LOW-PASS RESPONSE

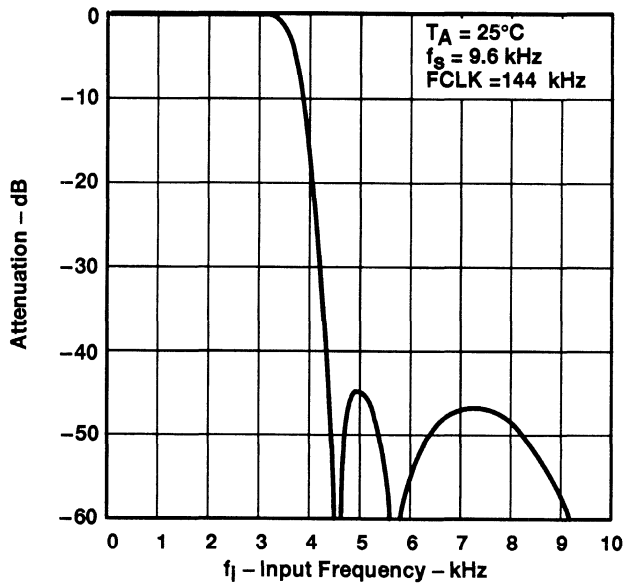


Figure 5-8

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{144}$

DAC LOW-PASS RESPONSE

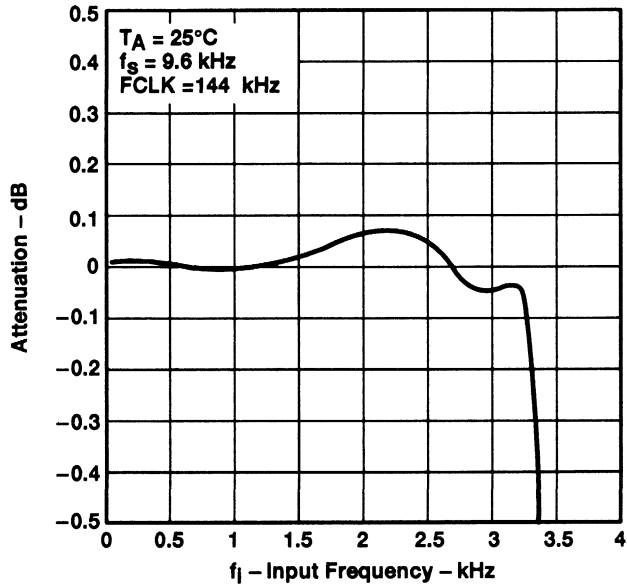


Figure 5-9

DAC LOW-PASS GROUP DELAY

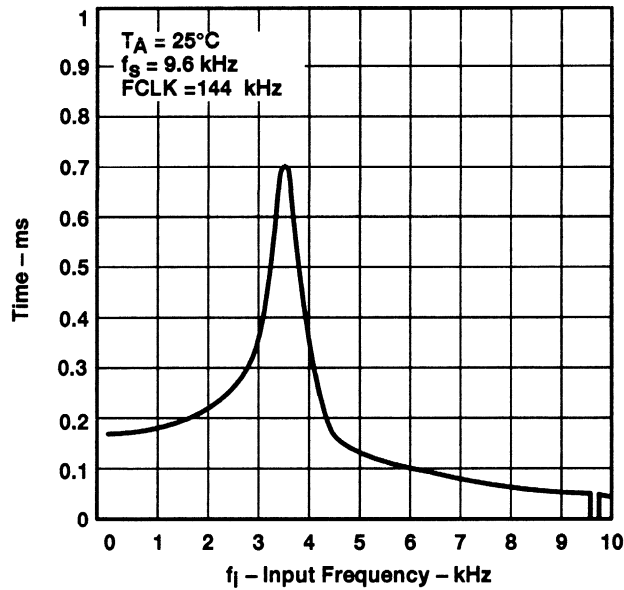


Figure 5-10

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times FCLK\text{ (kHz)}}{144}$

DAC (sin x)/x CORRECTION FILTER RESPONSE

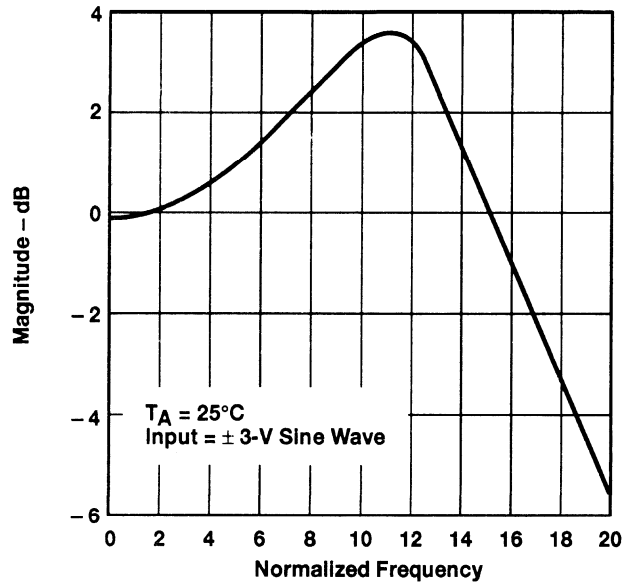


Figure 5-11

DAC (sin x)/x CORRECTION FILTER RESPONSE

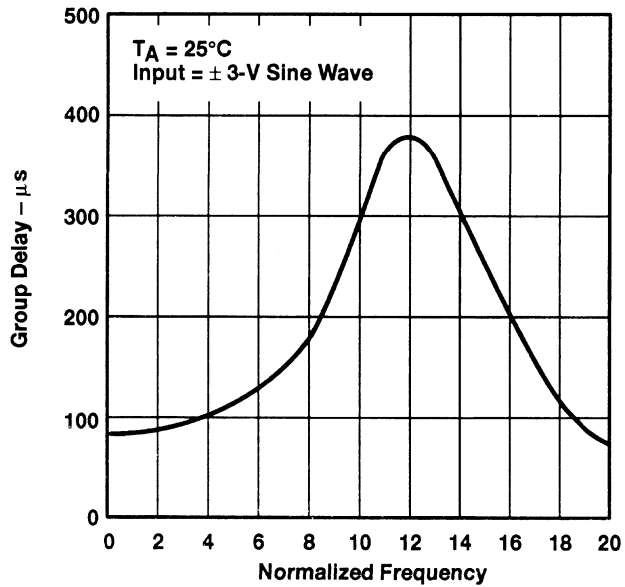


Figure 5-12

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{288}$

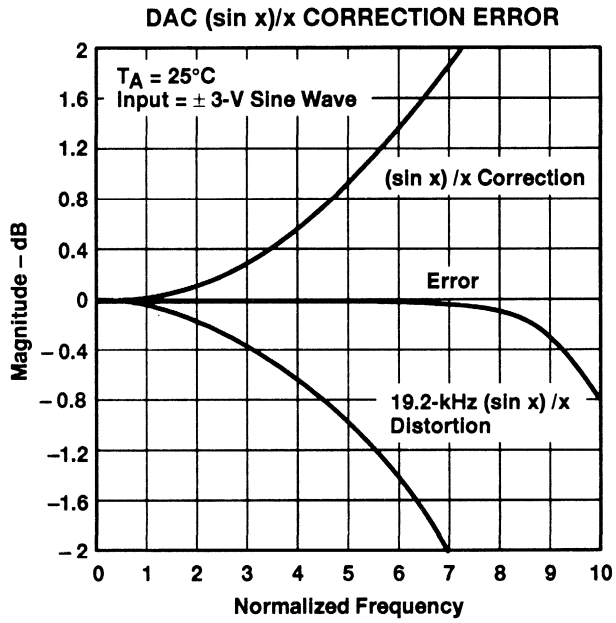


Figure 5-13

NOTE : Absolute Frequency (kHz) = $\frac{\text{Normalized Frequency} \times \text{FCLK (kHz)}}{288}$

6 Application Information

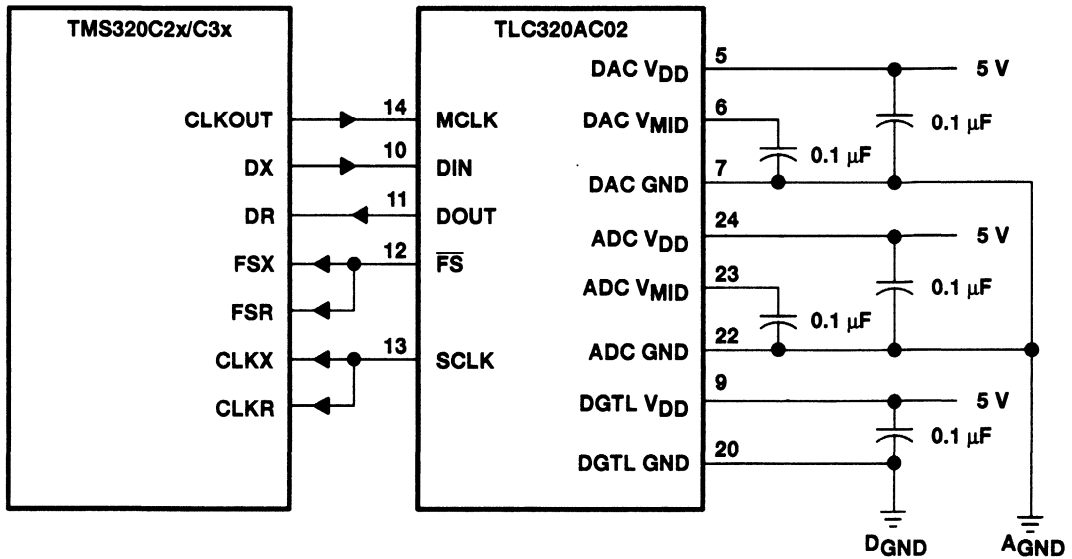


Figure 6-1. Stand-Alone Mode (to DSP Interface)

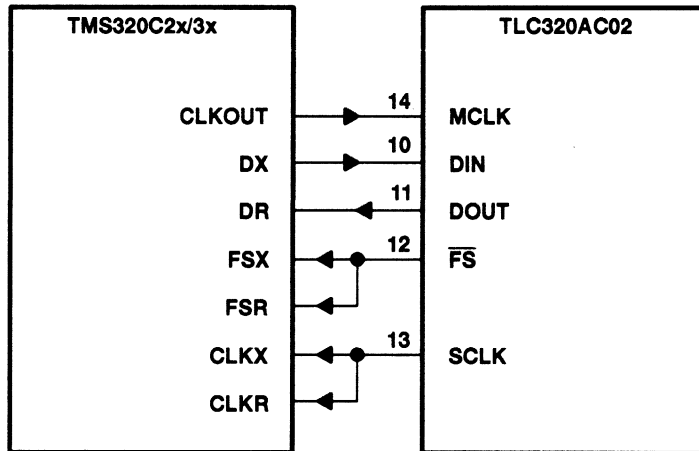
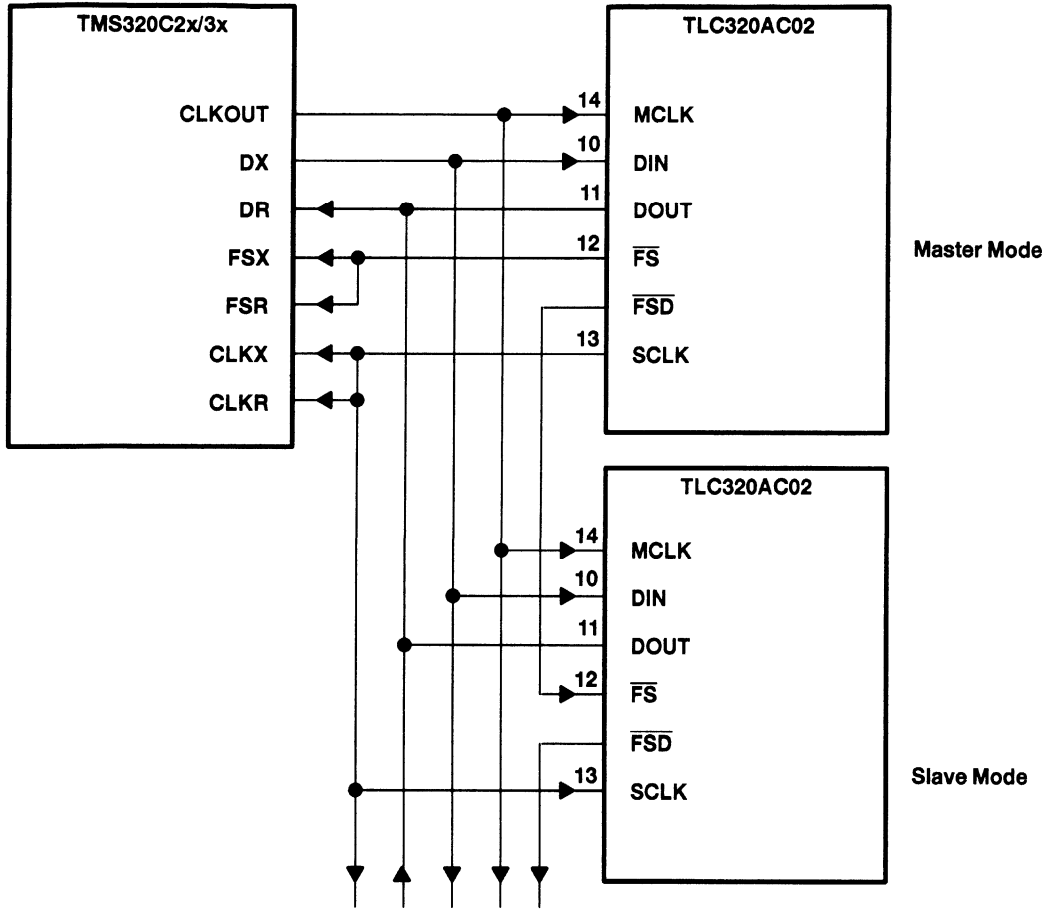


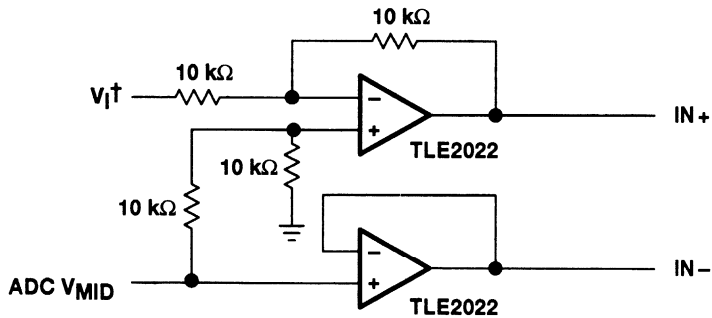
Figure 6-2. Codec Mode (to DSP Interface)

Terminal numbers shown are for the FN package.



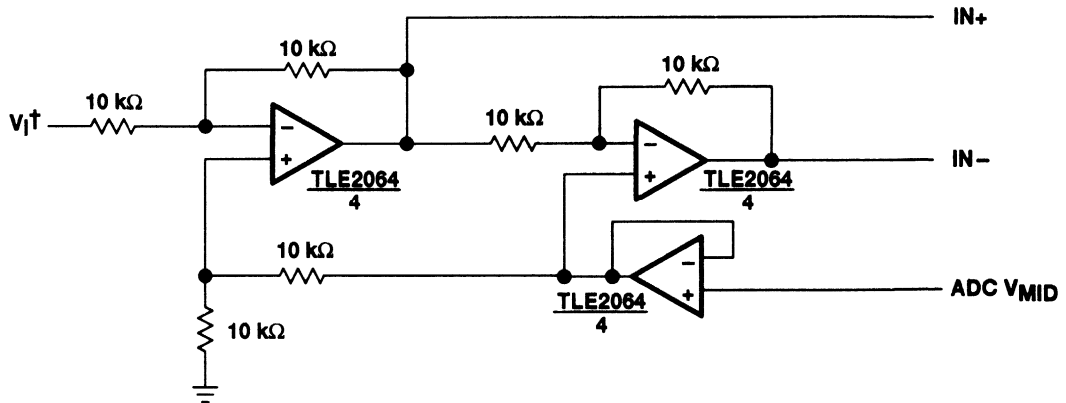
Terminal numbers shown are for the FN package.

Figure 6-3. Master With Slave (to DSP Interface)



† The V_1 source must be capable of sinking a current equal to $[ADC V_{MID} + |V_1|_{(max)}]/10 \text{ k}\Omega$.

Figure 6-4. Single-Ended Input (Ground Referenced)



† The V_I source must be capable of sinking a current equal to $[(ADC V_{MID}/2) + |V_I|(\max)]/10\text{ k}\Omega$.

Figure 6-5. Single-Ended to Differential Input (Ground Referenced)

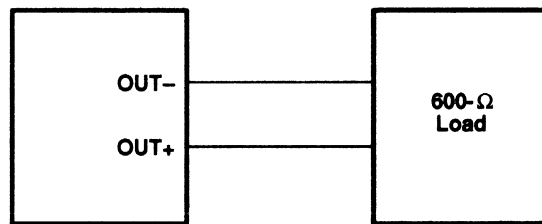
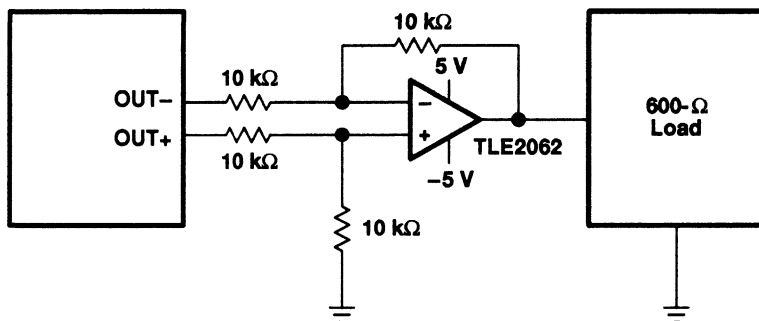


Figure 6-6. Differential Load



NOTE: When a signal is changed from a single supply with a nonzero reference system to a grounded load, the operational amplifier must be powered from plus and minus supplies or the load must be capacitively coupled.

Figure 6-7. Differential Output Drive (Ground Referenced)

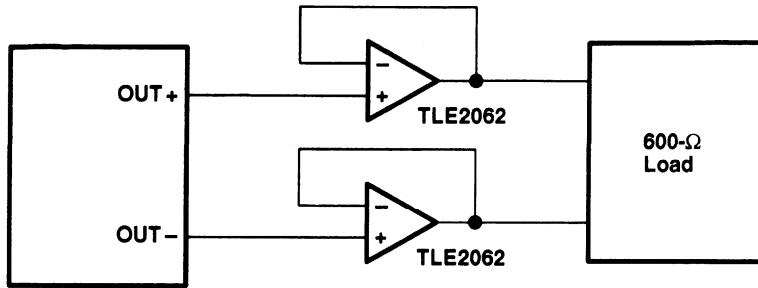
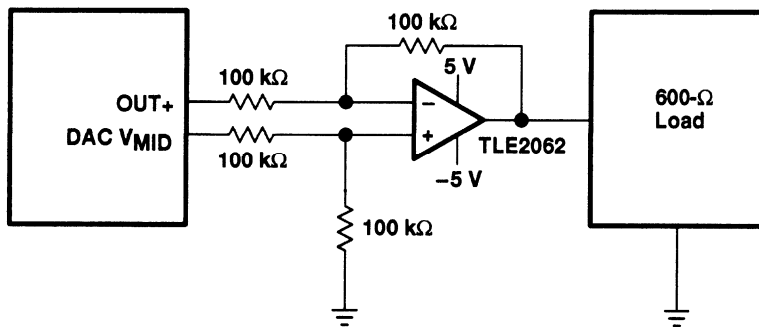


Figure 6-8. Low-Impedance Output Drive



NOTE: When a signal is changed from a single supply with a nonzero reference system to a grounded load, the operational amplifier must be powered from plus and minus supplies or the load must be capacitively coupled.

Figure 6-9. Single-Ended Output Drive (Ground Referenced)

Appendix A

Primary Control Bits

The function of the primary-word control bits D01 and D00 and the hardware terminals FC0 and FC1 are shown below. Any combinational state of D01, D00, FC1, and FC0 not shown is ignored.

CONTROL FUNCTION OF CONTROL BITS

BITS		TERMINALS		DESCRIPTION
D01	D00	FC1	FC0	
0	0	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.
0	0	0	1	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of the next internal \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods equal to the value contained in the A' register. If the A' register value is negative, the internal falling edge of \overline{FS} occurs earlier.
0	0	1	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of the next internal \overline{FS} , the next ADC/DAC sample time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, the internal falling edge of \overline{FS} occurs later.
0	0	1	1	On the next falling edge of the primary \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. When FC0 and FC1 are both taken high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS} .
0	1	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of D01 and D00 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, the falling edge of \overline{FS} occurs earlier.
1	0	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of D01 and D00. On the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, the internal falling edge of \overline{FS} occurs later.
1	1	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT. When D00 and D01 are both high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS} .

CONTROL FUNCTION OF CONTROL BITS (CONTINUED)

BITS		TERMINALS		DESCRIPTION
D01	D00	FC1	FC0	
0	1	1	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>The phase adjustment is determined by the state of D01 and D00 such that on the next rising edge of \overline{FS}, the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs earlier.</p> <p>When FC0 and FC1 are both taken high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p>
1	0	1	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>The phase adjustment is determined by the state of D01 and D00. On the next rising edge of \overline{FS}, the next ADC/DAC sample time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs later.</p> <p>When FC0 and FC1 are both taken high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p>
1	1	1	1	<p>On the next falling edge of the primary \overline{FS}, the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When FC1 and FC0 are both high or D01 and D00 are both high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary \overline{FS} occurs at 1/2 the sampling time measured from the falling edge of the primary \overline{FS}.</p>
1	1	0	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02, to DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When D00 and D01 are high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p> <p>The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS}, the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs earlier.</p>
1	1	1	0	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 to DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When D00 and D01 are high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary frame sync occurs at 1/2 the sampling time as measured from the falling edge of the primary \overline{FS}.</p> <p>The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS}, the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs earlier.</p>
1	1	1	1	<p>On the next falling edge of \overline{FS}, the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.</p> <p>When FC1 and FC0 are both high or D01 and D00 are both high, the AIC initiates a secondary \overline{FS} to receive a secondary control word at DIN. The secondary \overline{FS} occurs at 1/2 the sampling time measured from the falling edge of the primary \overline{FS}.</p>

Appendix B

Secondary Communications

The function of the control bits DS15 and DS14 and the hardware terminals FC0 and FC1 are shown below. Any combinational state of DS15, DS14, FC1, and FC0 not shown is ignored.

CONTROL FUNCTION OF SECONDARY COMMUNICATION

BITS		TERMINALS		
DS15	DS14	FC1	FC0	
0	0	Ignored		On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.
0	1	Ignored		On the next falling edge of the \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of DS15 and DS14 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs earlier.
1	0	Ignored		On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of D01 and D00. On the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs later.
1	1	0	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.
1	1	0	1	On the next falling edge of the \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs later by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs earlier.
1	1	1	0	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT. The phase adjustment is determined by the state of FC1 and FC0 such that on the next rising edge of \overline{FS} , the next ADC/DAC sampling time occurs earlier by the number of MCLK periods determined by the value contained in the A' register. If the A' register value is negative, \overline{FS} occurs later.
1	1	1	1	On the next falling edge of \overline{FS} , the AIC receives DAC data D15–D02 at DIN and transmits the ADC data D15–D00 from DOUT.

Appendix C

TLC320AC01C/TLC320AC02C Specification Comparisons

Texas Instruments manufactures the TLC320AC01C and the TLC320AC02C specified for the 0°C to 70°C commercial temperature range and the TLC320AC02I specified for the -40°C to 85°C temperature range. The TLC320AC02C and TLC320AC02I operate at a relaxed TLC320AC01C specification. The differences are listed in the following tables.

ADC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted) (see Note 1)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = 6\text{ dB}$		$A_V = 12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
TLC320AC01	$V_I = -6\text{ dB to } -1\text{ dB}$	68		—		—		dB
TLC320AC02		64		—		—		
TLC320AC01	$V_I = -12\text{ dB to } -6\text{ dB}$	63		68		—		
TLC320AC02		59		64		—		
TLC320AC01	$V_I = -18\text{ dB to } -12\text{ dB}$	57		63		68		
TLC320AC02		56		59		64		
TLC320AC01	$V_I = -24\text{ dB to } -18\text{ dB}$	51		57		63		
TLC320AC02		50		56		59		
TLC320AC01	$V_I = -30\text{ dB to } -24\text{ dB}$	45		51		57		
TLC320AC02		44		50		56		
TLC320AC01	$V_I = -36\text{ dB to } -30\text{ dB}$	39		45		51		
TLC320AC02		38		44		50		
TLC320AC01	$V_I = -42\text{ dB to } -36\text{ dB}$	33		39		45		
TLC320AC02		32		38		44		
TLC320AC01	$V_I = -48\text{ dB to } -42\text{ dB}$	27		33		39		
TLC320AC02		26		32		38		

NOTE 1: The analog input test signal is a 1020-Hz sine wave with 0 dB = 6 V peak to peak as the reference level for the analog input signal.

DAC Channel Signal-to-Distortion Ratio, $V_{DD} = 5\text{ V}$, $f_s = 8\text{ kHz}$ (Unless Otherwise Noted) (see Note 2)

PARAMETER	TEST CONDITIONS	$A_V = 0\text{ dB}$		$A_V = -6\text{ dB}$		$A_V = -12\text{ dB}$		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	
TLC320AC01	$V_O = -6\text{ dB to }0\text{ dB}$	68		—		—		dB
TLC320AC02		64		—		—		
TLC320AC01	$V_O = -12\text{ dB to }-6\text{ dB}$	63		68		—		
TLC320AC02		59		64		—		
TLC320AC01	$V_O = -18\text{ dB to }-12\text{ dB}$	57		63		68		
TLC320AC02		56		59		64		
TLC320AC01	$V_O = -24\text{ dB to }-18\text{ dB}$	51		57		63		
TLC320AC02		50		56		59		
TLC320AC01	$V_O = -30\text{ dB to }-24\text{ dB}$	45		51		57		
TLC320AC02		44		50		56		
TLC320AC01	$V_O = -36\text{ dB to }-30\text{ dB}$	39		45		51		
TLC320AC02		38		44		50		
TLC320AC01	$V_O = -42\text{ dB to }-36\text{ dB}$	33		39		45		
TLC320AC02		32		38		44		
TLC320AC01	$V_O = -48\text{ dB to }-42\text{ dB}$	27		33		39		
TLC320AC02		26		32		38		

NOTE 2: The input signal, V_I , is the digital equivalent of a 1020-Hz sine wave (full-scale analog output at full-scale digital input = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is 600 Ω from OUT + to OUT -.

**System Distortion, ADC Channel Attenuation, $V_{DD} = 5\text{ V}$, $f_S = 8\text{ kHz}$,
FCLK = 144 kHz (Unless Otherwise Noted)**

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
TLC320AC01	Second harmonic	Differential input (see Note 3)	70		dB
TLC320AC02			64		dB
TLC320AC01	Third harmonic and higher harmonics		70		dB
TLC320AC02			64		dB

NOTE 3: The input signal is a 1020 Hz-sine wave for the ADC channel. Harmonic distortion is defined for an input level of -1 dB .

**System Distortion, DAC Channel Attenuation, $V_{DD} = 5\text{ V}$, $f_S = 8\text{ kHz}$,
FCLK = 144 kHz (Unless Otherwise Noted)**

PARAMETER		TEST CONDITIONS	MIN	MAX	UNIT
TLC320AC01	Second harmonic	Differential output (see Note 4)	70		dB
TLC320AC02			64		dB
TLC320AC01	Third harmonic and higher harmonics		70		dB
TLC320AC02			64		dB

NOTE 4: The input signal is the digital equivalent of a 1020-Hz sine wave (digital full scale = 0 dB). The nominal differential DAC channel output with this input condition is 6 V peak to peak. The load impedance for the DAC output buffer is $600\ \Omega$ from $\text{OUT}+$ to $\text{OUT}-$. Harmonic distortion is specified for a signal input level of 0 dB .

TLC320AD55C ***Data Manual***

Sigma-Delta Analog Interface Circuit



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1 Introduction

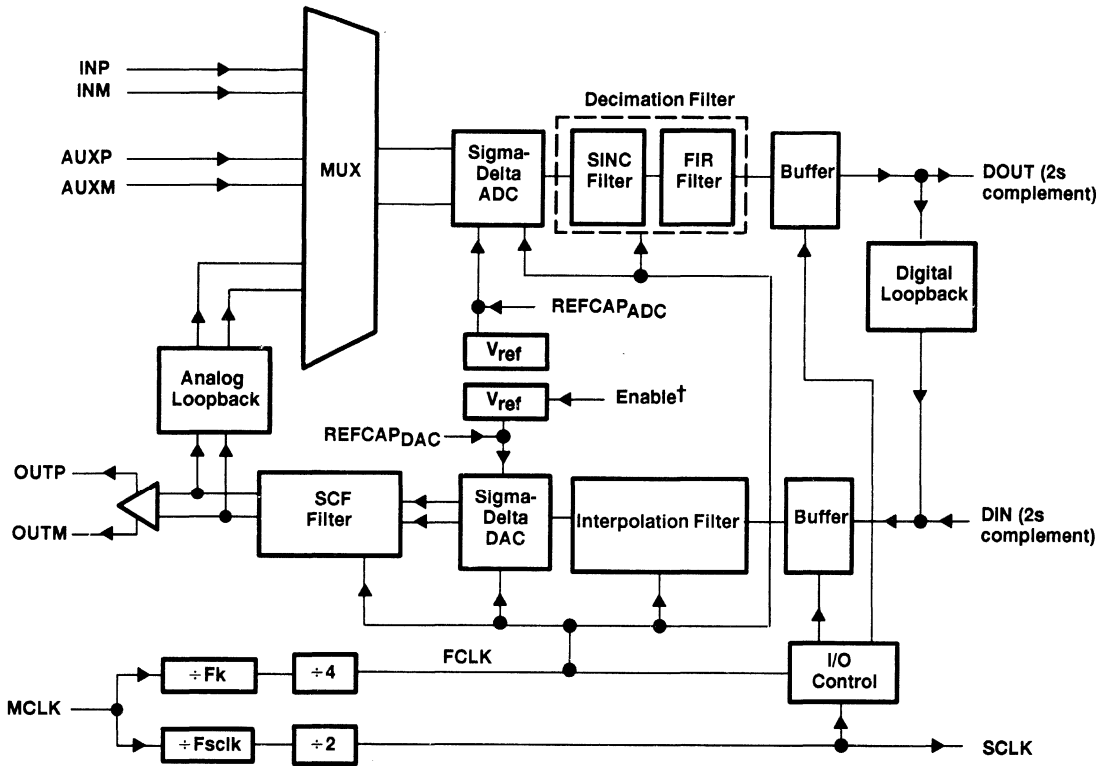
The TLC320AD55C provides high resolution low-speed signal conversion from digital-to-analog (D/A) and from analog-to-digital (A/D) using oversampling sigma-delta technology. This device consists of two, serial, synchronous conversion paths (one for each data direction) and includes an interpolation filter before the digital-to-analog converter (DAC) and a decimation filter after the analog-to-digital converter (ADC) (see Figure 1–1). Other overhead functions provide analog filtering and on-chip timing and control. The sigma-delta architecture produces high resolution, analog-to-digital and digital-to-analog conversion at low system speeds and low cost.

The options and the circuit configurations of this device can be programmed through the serial interface. The options include reset, power-down, communications protocol, serial clock rate, signal sampling rate, and test mode as outlined in Appendix A. The circuit configurations could include a selection of input ports to the ADC, analog loopback, digital loopback, decimator sinc filter output, decimator finite-duration impulse-response (FIR) filter output, interpolator sinc filter output, and interpolator FIR filter output. The TLC320AD55C is characterized for operation from 0°C to 70°C.

1.1 Features

- Single 5-V power supply
- Power dissipation (P_D) of 150 mW maximum in the operating mode
- Power-down mode to 1 mW
- General-purpose 16-bit signal processing
- 2s-complement format
- Serial port interface
- Minimum 80-dB harmonic distortion plus noise
- Differential architecture
- Internal reference voltage (V_{ref})
- Internal 64 × oversampling
- Analog output with programmable gain of 1, 1/2, 1/4, and 0 (squelch)
- Phone-mode output control
- Variable conversion rate selected as $MCLK/(F_k \times 256)$, $F_k = 1, 2, 3, \dots, 256$
- System test mode:
 - Digital loopback test
 - Analog loopback test

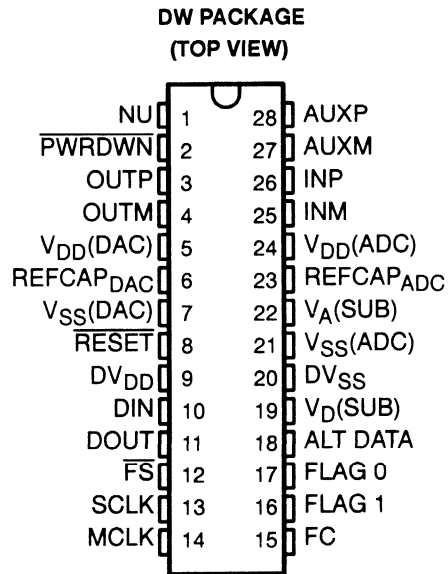
1.2 Functional Block Diagram



† See control 3 register in Appendix A.

Figure 1–1. Functional Block Diagram

1.3 Terminal Assignments



NU – Make no external connection

Figure 1–2. Terminal Assignments

1.4 Ordering Information

T _A	PACKAGE
	SMALL OUTLINE (DW)
0°C to 70°C	TLC320AD55CDW

1.5 Terminal Functions

TERMINALS NAME	NO.	I/O	DESCRIPTION
AUXM	27	I	Inverting input to auxiliary analog input
AUXP	28	I	Noninverting input to auxiliary analog input
ALT DATA	18	I	Signals on ALT DATA are routed to DOUT during secondary communication when phone mode is enabled.
DIN	10	I	Data input. DIN receives the DAC input data and command information from the DSP and is synchronized to SCLK.
DOUT	11	O	Data output. DOUT transmits the ADC output bits and is synchronized to SCLK. DOUT is at Hi-Z when \overline{FS} is not activated.
DV _{DD}	9	I	Digital power supply
DV _{SS}	20	I	Digital ground
FC	15	I	Function control. FC is sampled and latched on the rising edge of FS for the primary serial communication. Refer to Section 3 Serial Communications for more details.
FLAG 0	17	O	During phone mode, FLAG 0 contains the value set in control 2 register.
FLAG 1	16	O	During phone mode, FLAG 1 contains the value set in control 2 register.
\overline{FS}	12	O	Frame sync. When \overline{FS} goes low, the serial communication port is activated. In all serial transmission modes, \overline{FS} is held low during bit transmission. Refer to Section 3 Serial Communications for a detailed description.
INM	25	I	Inverting input to analog input
INP	26	I	Noninverting input to analog input
MCLK	14	I	Master clock. MCLK derives the internal clocks of the sigma-delta analog interface circuit.
OUTM	4	O	Inverting output of the DAC analog power amplifier. Functionally identical with and complementary to OUTP. OUTM and OUTP can drive 600 Ω differentially. OUTM should not be used alone for single-ended operation.
OUTP	3	O	Noninverting output of the DAC analog power amplifier. OUTM and OUTP can drive 600 Ω differentially. OUTP should not be used alone for single-ended operation.
\overline{PWRDWN}	2	I	Power down. When \overline{PWRDWN} is pulled low, the device goes into a power-down mode; the serial interface is disabled and most of the high-speed clocks are disabled. However, all of the registers' values are sustained and the device resumes full power operation without reinitialization when \overline{PWRDWN} is pulled high again. \overline{PWRDWN} resets the counters only and preserves the programmed register contents. Refer to Section 2.2.1.3 Software and Hardware Power-Down.
REFCAP _{ADC}	23	O	Analog-reference voltage connection for external capacitor for the ADC. The nominal voltage on REFCAP _{ADC} is 3.4 V. A buffer must be used when this voltage is used externally. REFCAP _{ADC} is not to be used as the mid-supply voltage reference for single-ended operation.
REFCAP _{DAC}	6	O	Analog-reference voltage connection for external capacitor for the DAC. The nominal voltage on REFCAP _{DAC} is 3.4 V. A buffer must be used when this voltage is used externally.
RESET	8	I	Reset. The reset function initializes all of the internal registers to their default values. The serial port can be configured to the default state accordingly. Refer to Appendix A Table A-2 Control 1 Register and Section 2.2.1 Reset and Power-Down for more detailed descriptions.
SCLK	13	O	Shift clock. SCLK is derived from MCLK and clocks serial data into DIN and out of DOUT.

NOTE 1: All digital inputs and outputs are TTL compatible unless otherwise noted.

1.5 Terminal Functions (Continued)

TERMINALS		I/O	DESCRIPTION
NAME	NO.		
V _A (SUB)	22	I	Analog substrate. V _A (SUB) must be grounded.
V _D (SUB)	19	I	Digital substrate. V _D (SUB) must be grounded.
V _{DD} (ADC)	24	I	Analog ADC path supply
V _{DD} (DAC)	5	I	Analog DAC path supply
V _{SS} (ADC)	21	I	Analog ADC path ground
V _{SS} (DAC)	7	I	Analog DAC path ground

NOTE 1: All digital inputs and outputs are TTL compatible unless otherwise noted.

1.6 Definitions and Terminology

Data Transfer Interval	The time during which data is transferred from DOUT and to DIN. The interval is 16 shift clocks and this data transfer is initiated by the falling edge of the frame-sync signal.
Signal Data	The input signal and all of the converted representations through the ADC channel and return through the DAC channel to the analog output. This is contrasted with the purely digital software control data.
Primary Communications	The digital data transfer interval. Since the device is synchronous, the signal data words from the ADC channel and to the DAC channel occur simultaneously.
Secondary Communications	The digital control and configuration data transfer interval into DIN and the register read data cycle from DOUT. The data transfer interval occurs when requested by hardware or software.
Frame Sync	The falling edge of the signal that initiates the data transfer interval. The primary frame sync starts the primary communications, and the secondary frame sync starts the secondary communications.
Frame Sync and Sampling Period	The time between falling edges of successive primary frame-sync signals.
f _s	The sampling frequency that is the reciprocal of the sampling period.
Frame-Sync Interval	The time period occupied by 16 shift clocks. It goes high on the sixteenth rising edge of SCLK after the falling edge of the frame sync.
ADC Channel	All signal processing circuits between the analog input and the digital conversion results at DOUT.
DAC Channel	All signal processing circuits between the digital data word applied to DIN and the differential output analog signal available at OUTP and OUTM.
Host	Any processing system that interfaces to DIN, DOUT, SCLK, or \overline{FS} .
Dxx	A bit position in the primary data word (xx is the bit number).
DSxx	A bit position in the secondary data word (xx is the bit number).
d	The alpha character d is used to represent valid programmed or default data in the control register format (see secondary serial communications) when discussing other data bit portions of the register.
X	The alpha character X represents a don't-care bit position within the control register format.
FIR	Finite-duration impulse response.

1.7 Register Functional Summary

There are six data and control registers that are used as follows:

- Register 0 The No-op register. The 0 register allows secondary requests without altering any other register.
- Register 1 The control 1 register. The data in this register controls:
- The software reset
 - The software power-down
 - Selection of the normal or auxiliary analog inputs
 - The output amplifier gain (1, 1/2, 1/4, or squelch)
 - Selection of the analog loopback
 - Selection of the digital loopback
 - 16-bit or 15-bit mode of operation
- Register 2 The control 2 register. The data in this register:
- Contains the output flag indicating a decimator FIR filter overflow
 - Contains Flag 0 and Flag 1 output values for use in the phone mode
 - Selects the phone mode
 - Selects or bypasses the decimation FIR filter
 - Selects or bypasses the interpolater FIR filter
- Register 3 The Fk divide register. This register controls the filter clock rate and the sample period.
- Register 4 The Fclk divide register. This register controls the shift (data) clock rate.
- Register 5 The control 3 register. This register enables and disables the DAC reference.

2 Functional Description

2.1 Device Functions

The following sections describe the functions of the device.

2.1.1 Operating Frequencies

The sampling (conversion) frequency is derived from the master clock (MCLK) input by the following equation:

$$f_s = \text{Sampling (conversion) frequency} = \frac{\text{MCLK frequency}}{(\text{Fk register value}) \times 256}$$

The inverse is the time between the falling edges of two successive primary frame-synchronization signals and it is the conversion period.

The input and output data clock (SCLK) is given by:

$$\text{SCLK frequency} = \frac{\text{MCLK frequency}}{(\text{Fsk register value}) \times 2}$$

2.1.2 ADC Signal Channel

To produce excellent common-mode rejection of unwanted signals, the analog signal is processed differentially until it is converted to digital data.

The ADC converts the signal into discrete output digital words in 2s-complement format, corresponding to the analog-signal value at the sampling time. These 16-bit digital words, representing sampled values of the analog input signal, are clocked out of the serial port, DOUT, during the frame-sync interval (one word for each primary communication interval). During secondary communications, the data previously programmed into the registers can be read out with the appropriate register address, and the read bit set to 1. When a register read is not requested, all 16 bits are 0 in the secondary word.

2.1.3 DAC Signal Channel

DIN receives the 16-bit serial data word (2s complement) from the host during the primary communications interval and latches the data on the seventeenth rising edge of SCLK. The data are converted to an analog voltage by the DAC and then passed through a $(\sin x)/x$ correction circuit and a smoothing filter. An output buffer with three software-programmable gains (0 dB, -6 dB, and -12 dB) drives the differential outputs OUTP and OUTM. A squelch mode can also be programmed for the output buffer. During secondary communications, the configuration program data are read into the device control registers.

2.1.4 Serial Interface

The digital serial interface consists of the shift clock, the frame synchronization signal, the ADC-channel data output, and the DAC-channel data input. During the primary 16-bit frame synchronization interval, SCLK transfers the ADC channel results from DOUT and transfers 16-bit DAC data into DIN.

During the secondary frame-synchronization interval, the SCLK transfers the register read data from DOUT when the read bit is set to a one. In addition, SCLK transfers control and device parameter information into DIN. The functional sequence is shown in Figure 3-1.

2.1.5 Register Programming

All register programming occurs during secondary communications, and data are latched and valid on the rising edge of the frame-sync signal. When the default value for a particular register is desired, that register does not need to be addressed during secondary communications. The no-op command addresses the no-op register (register 0), and register programming does not take place during this communication.

DOUT is released from the high-impedance state on the falling edge of the primary or secondary frame-sync interval. In addition, each register can be read back during DOUT secondary communications by setting the read bit D13 to 1 in the addressed register (refer to Appendix A). When the register is in the read mode, no data can be written to the register during this cycle. To return this register to the write mode requires a subsequent secondary communication.

2.1.6 Sigma-Delta ADC

The sigma-delta ADC is a fourth-order, sigma-delta modulator with 64-times oversampling. The ADC provides high-resolution, low-noise performance using oversampling techniques.

2.1.7 Decimation Filter

The decimation filter reduces the digital data rate to the sampling rate. This is accomplished by decimating with a ratio of 1:64. The output of this filter is a sixteen-bit, 2s-complement data word clocking at the sample rate.

NOTE

The sample rate is determined through a programmable relationship of $MCLK/(F_k \times 256)$, $F_k = 1, 2, 3, \dots, 256$

2.1.8 Sigma-Delta DAC

The sigma-delta DAC is a fourth-order, sigma-delta modulator with 64-times oversampling. The DAC provides high-resolution, low-noise performance from a one-bit converter using oversampling techniques.

2.1.9 Interpolation Filter

The interpolation filter resamples the digital data at a rate of 64 times the incoming sample rate. The high-speed data output from this filter is then used in the sigma-delta DAC.

2.1.10 Switched-Capacitor Filter (SCF)

A switched-capacitor filter network is implemented on the analog output to provide low-pass operation with high rejection in the stop band.

2.1.11 Analog/Digital Loopback

The loopbacks provide a means of testing the ADC/DAC channels and can be used for in-circuit, system-level tests. The loopbacks feed the appropriate output to the corresponding input on the device.

The test capabilities include an analog loopback between the two analog paths and a digital loopback between the two digital paths. Each loopback is enabled by setting the D1 or D2 bit in control 1 register (see Appendix A).

2.1.12 DAC Voltage Reference Enable

The DAC voltage reference can be disabled through the control 3 register. This allows the use of an external voltage reference applied to the DAC channel modulator. By supplying an external reference, the user can scale the output voltage range of this channel. The internal reference value is 3.6 V which provides a 6-V, peak-to-peak, differential output. The ratio of an external reference to the internal reference determines the output voltage range of the DAC channel as shown in the following equation:

$$V_{O(PP)} = \frac{V(\text{EXT REF})}{3.6} \times 6 \text{ V}$$

NOTE

The distortion and noise specifications listed in Section 4 Specifications apply only under the following condition:

$$\frac{V(\text{EXT REF})}{3.6} \leq 1$$

2.1.13 FIR Overflow Flag

The decimator FIR filter provides an overflow flag to the control 2 register to indicate that the input to the filter has exceeded the range of the internal filter calculations. When this bit is set in the register, it remains set until the register is read by the user. Reading this value always resets the overflow flag.

2.2 Terminal Descriptions

The following sections describe the terminal functions.

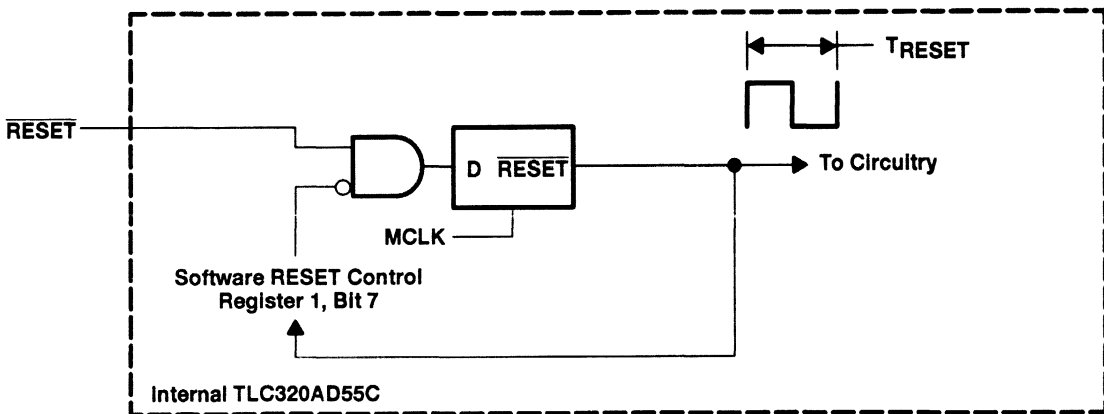
2.2.1 Reset and Power-Down

2.2.1.1 Reset

As shown in Figure 2–1, the TLC320AD55C resets both the internal counters and registers, including the programmed registers, in two ways:

- By applying a low-going reset pulse to the $\overline{\text{RESET}}$ terminal
- By writing to the programmable software reset bit (D07 in control 1 register)

$\overline{\text{PWRDWN}}$ resets the counters only and preserves the programmed register contents. The DAC resets to the 15-bit mode.



NOTE A: $\overline{\text{RESET}}$ to circuitry is at least 6 MCLK periods long and releases on the positive edge of MCLK.

Figure 2–1. Reset Function

2.2.1.2 Conditions of Reset

The two internal reset signals used for the reset and synchronization functions are:

- Counter reset – This signal resets all flip-flops and latches that are not externally programmed, with the exception of those generating the reset pulse itself. Additionally, this signal resets the software power-down bit.

Counter reset = $\overline{\text{RESET}}$ terminal or reset bit or $\overline{\text{PWRDWN}}$ terminal

- Register reset – This signal resets all flip-flops and latches that are not reset by the counter reset, except those generating the reset pulse itself.

Register reset = $\overline{\text{RESET}}$ terminal or reset bit

Both reset signals are at least six MCLK periods long (T_{RESET}) and release on the trailing edge of MCLK.

2.2.1.3 Software and Hardware Power-Down

Given the definitions above, the software-programmed power-down condition is cleared by programming the **software** bit (control 1 register bit 6) to a 0 or is cleared by cycling the power to the device, bringing $\overline{\text{PWRDWN}}$ low, or bringing $\overline{\text{RESET}}$ low (see Figure 2–2).

$\overline{\text{PWRDWN}}$ removes power to the entire chip. The software-programmable, power-down bit only removes power from the analog section of the chip, which allows a software power-up function. Cycling the power-down terminal from high to low and back to high resets all flip-flops and latches that are not externally programmed, thereby preserving the register contents with the exception that the software power-down bit is cleared.

When $\overline{\text{PWRDWN}}$ is not being used, it should be tied high [$V_{\text{DD}}(\text{ADC})$ is preferred].

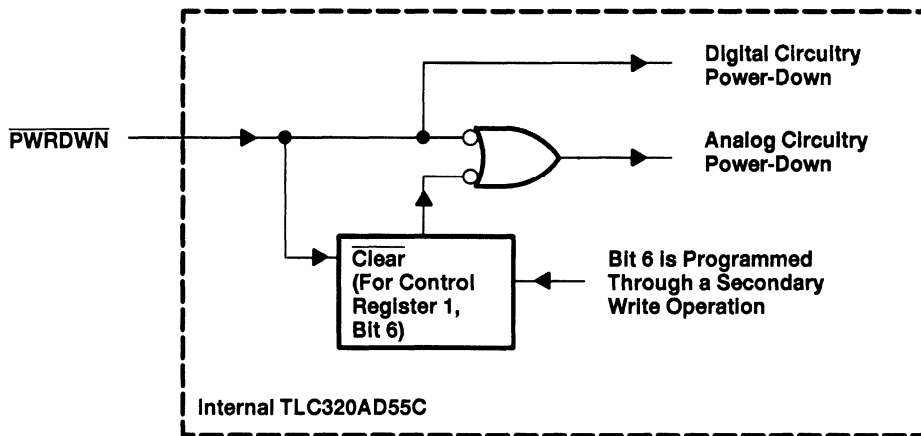


Figure 2–2. Internal Power-Down Logic

2.2.2 Master Clock Circuit

The clock circuit generates and distributes necessary clocks throughout the device. MCLK is the external master clock input. SCLK is derived from MCLK [$\text{SCLK} = \text{MCLK}/(\text{Fsc} \times 2)$, $\text{Fsc} = 1, 2, 3, \dots, 256$] in order to provide clocking of the serial communications between the device and a digital signal processor (DSP). The sample rate of the data paths is set as $\text{MCLK}/(\text{Fk} \times 256)$. Fk and Fsc are programmable register values used as divisors of MCLK. The default value for the Fk and Fsc register is 8 (decimal).

2.2.3 Data Out (DOUT)

DOUT is taken from the high-impedance state by the falling edge of the frame-sync signal. The most significant data bit then appears on DOUT.

DOUT is placed in a high-impedance state on the sixteenth rising edge of SCLK (internal or external) after the falling edge of the frame-sync signal. In the primary communication, the data word is the ADC conversion result. In the secondary communication, the data is the register read results when requested by the read/write ($\text{R}/\overline{\text{W}}$) bit with the eight MSBs set to zero (see the serial communications section). When a register read is not requested, the secondary word is all zeroes.

2.2.4 Data In (DIN)

In the primary communication, the data word is the input digital signal to the DAC channel. In the secondary communication, the data is the control and configuration data to set up the device for a particular function (see Section 3 Serial Communications).

2.2.5 Hardware Program Terminal (FC)

This input provides for hardware programming requests for secondary communication. It works in conjunction with the control bit D00 of the secondary data word. The signal on FC is latched 1/2 shift clock after the rising edge of the next internally generated primary frame-sync interval. FC should be tied low when not being used (see Section 3.2 Secondary Serial Communication).

2.2.6 Frame-Sync

The frame-sync signal indicates that the device is ready to send and receive data. The data transfer from DOUT and into DIN begins on the falling edge of the frame-sync signal.

The frame sync is generated internally and goes low on the rising edge of SCLK and remains low during the 16-bit data transfer.

2.2.7 Multiplexed Analog Input

The two differential analog inputs (INP and INM or AUXP and AUXM) are multiplexed into the sigma-delta modulator. The performance of the AUX channel is similar to the normal input channel.

2.2.8 Analog Input

The signal applied to the terminals INM and INP should be differential to preserve the device specifications (see Figure 2–3). A single-ended input signal should always be converted to a differential input signal prior to being used by the TLC320AD55C. The signal source driving the analog inputs (INM, INP, AUXM, AUXP) should have a low source-impedance for lowest noise performance and accuracy.

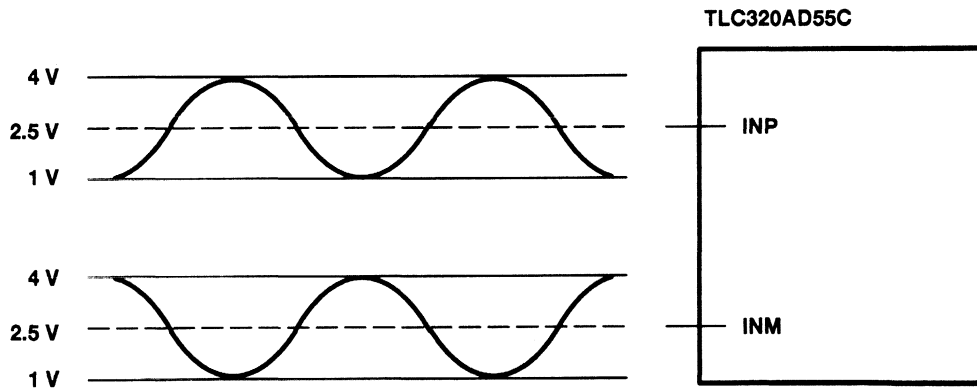


Figure 2–3. Differential Analog Input Configuration

3 Serial Communications

DOUT, DIN, SCLK, \overline{FS} , and FC are the serial communication signals. The digital output data from the ADC is taken from DOUT. The digital input data for the DAC is applied to DIN. The synchronizing clock for the serial communication data and the frame sync is taken from SCLK. The frame-synchronization pulse that encloses the ADC/DAC data transfer interval is taken from \overline{FS} . For signal (audio) data transmitted from the ADC or to the DAC, primary serial communication is used. To read or write words that control both the options and the circuit configurations of the device, secondary communication is used.

The purpose of the primary and secondary communications is to allow conversion data and control data to be transferred across the same serial port. A primary transfer is always dedicated to conversion data. A secondary transfer sets up and reads the register values described in Appendix A. A primary transfer occurs for every conversion period. A secondary transfer occurs only when requested. Two methods exist for requesting a secondary command. Terminal FC can request a secondary communication when it is asserted, or the LSB of the DAC data within a primary transfer can request a secondary communication. The selection of which method is enabled is provided in control 1 register (bit 0) as shown in Appendix A.

For all serial communications, the most significant bit is transferred first. For a 16-bit ADC word and a 16-bit DAC word, D15 is the most significant bit and D0 is the least significant bit. For a 15-bit DAC data word in the 16-bit primary communication, D15 is the most significant bit, D1 is the least significant bit, and D0 is used for the embedded function control. All digital data values are in 2s-complement format.

These logic signals are compatible with TTL-voltage levels and CMOS current levels.

3.1 Primary Serial Communication

Primary serial communication is used both to transmit and receive conversion signal data. The ADC word length is always 16 bits. The DAC word length depends on the status of D0 in the control 1 register. After power-up or reset, the device defaults to the 15-bit mode (not 16-bit mode). The DAC word length is 15 bits and the last bit of the primary 16-bit serial communication word is a function-control bit used to request secondary serial communications. In the 16-bit mode, all 16 bits of the primary communications word are used as data for the DAC and the hardware terminal FC must be used to request secondary communications.

Figure 3–1 shows the timing relationship for SCLK, \overline{FS} , DOUT and DIN in a primary communication. The timing sequence for this operation is as follows:

1. The TLC320AD55C takes \overline{FS} low.
2. One 16-bit word is transmitted from the ADC (DOUT) and one 16-bit word is received for the DAC (DIN).
3. The TLC320AD55C takes \overline{FS} high.

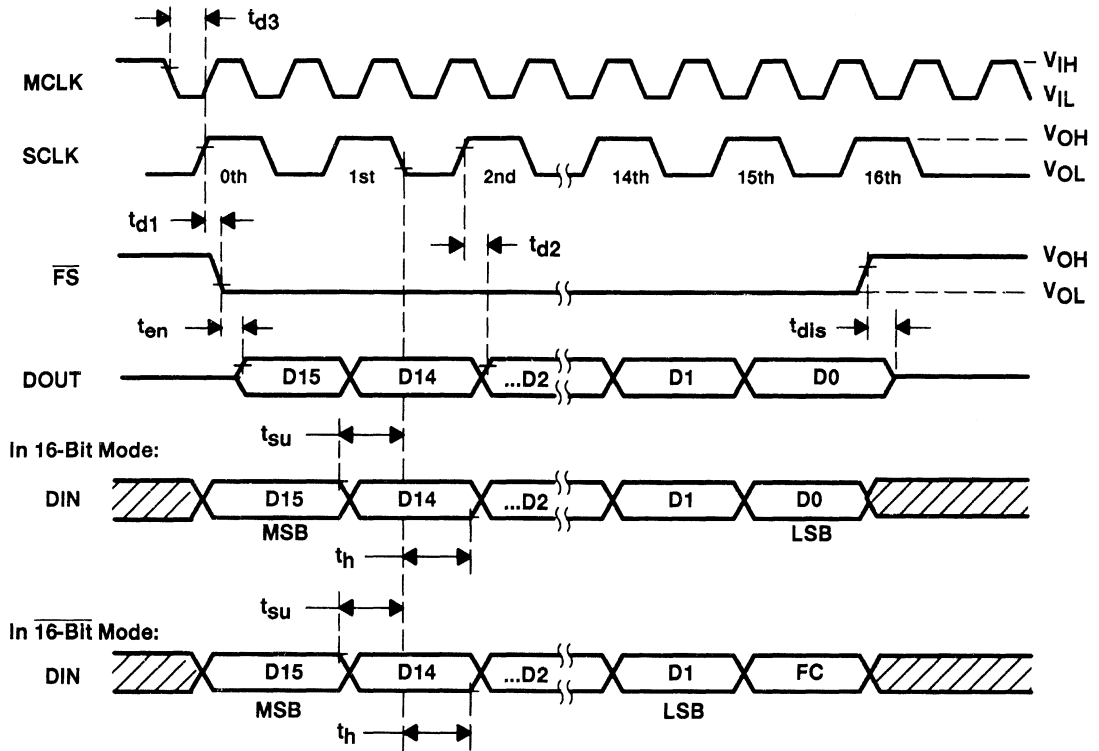


Figure 3–1. Primary Serial Communication Timing

When a secondary request is made through the LSB of the DAC data word ($\overline{16}$ -bit mode), the format shown in Figure 3–2 is used:

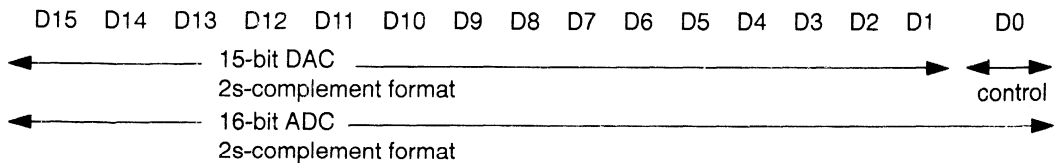


Figure 3–2. DAC and ADC Word Lengths

3.2 Secondary Serial Communication

Secondary serial communication reads or writes 16-bit words that program both the options and the circuit configurations of the device. All register programming occurs during secondary communications. Four primary and secondary communication cycles are required to program the four registers. When the default value for a particular register is desired, the user can omit addressing it during secondary communication. A no-op command addresses the no-op register (register 0), and no register programming takes place during this secondary communication.

There are two methods for initiating secondary communications (see Figure 3–3):

1) by asserting a high level on FC, or 2) by asserting the LSB of DIN 16-bit serial communication high while not in 16-bit mode (see control 1 register bit 0).

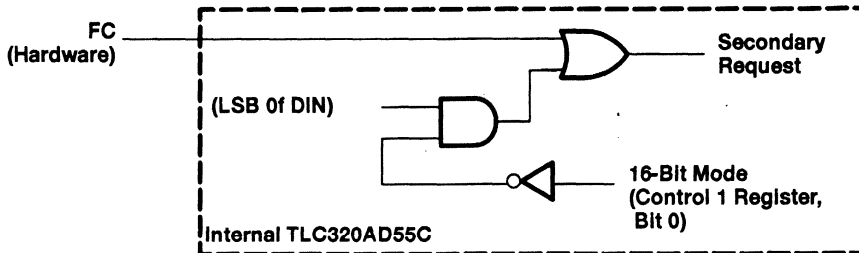


Figure 3–3. Hardware and Software Methods to Initiate a Secondary Request

1. Figures 3–5 and 3–6 show the two different methods by which FC requests secondary communication words as well as the timing for \overline{FS} , DOUT, DIN, and SCLK. The examples span two primary communication frames. Figure 3–5 shows the use of hardware function control.

During a secondary communication, a register can be written to or read from. When writing a value to a register, DIN contains the value to be written (see Figure 3–7). The data returned on DOUT is 00(hex). When performing a read function, DIN can still provide data to be written to an addressed register; however, DOUT contains the most recent value contained in the register addressed by DIN.

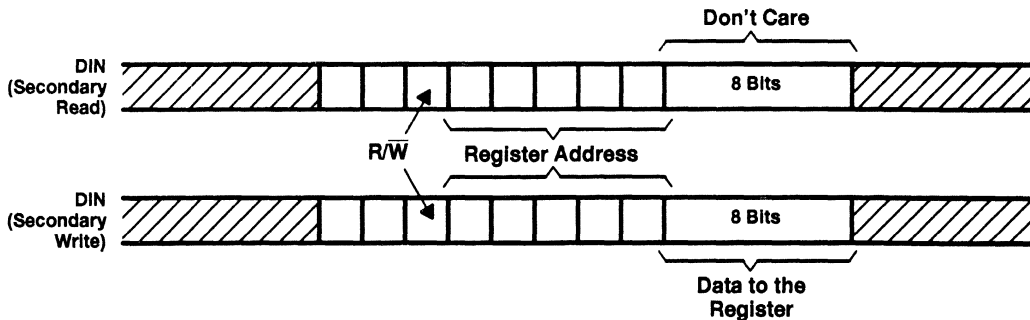


Figure 3–4. Secondary DIN Format

In Figure 3–5, FC clocks in and latches on the rising edge of frame sync (\overline{FS}). This causes the start of the secondary update 32 FCLKs (see Fk divide register, Appendix A) after the start of the primary communication frame. Read and write examples are shown for DIN and DOUT.

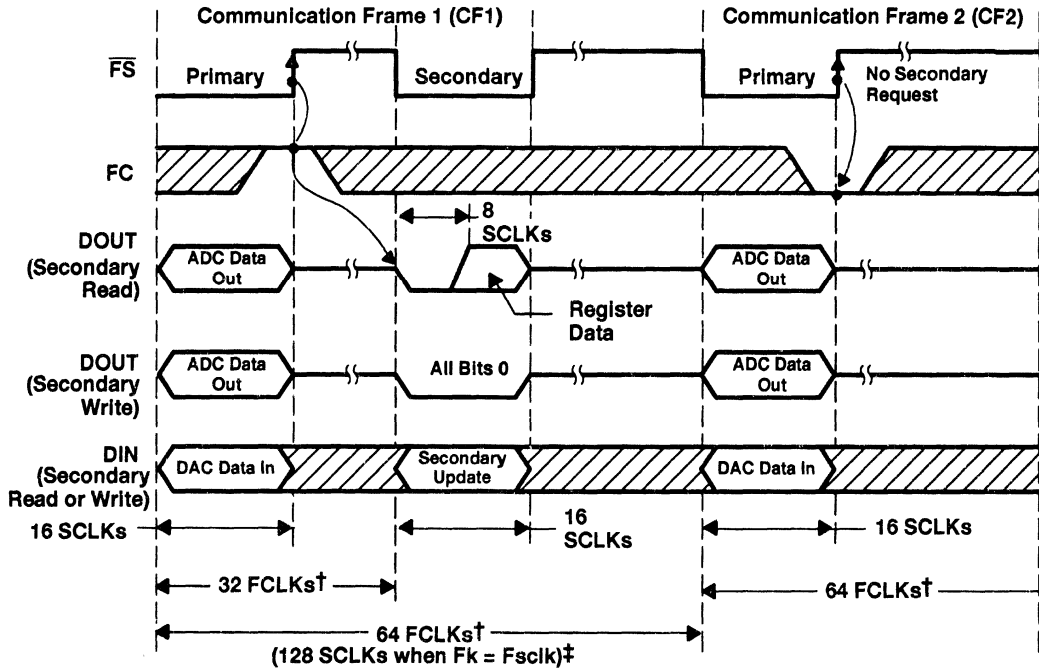
2. Figure 3–6 shows the use of software function control.

The software request for function control is typically used when the required resolution of the DAC channel is less than 16 bits. Then the least significant bit (D0) can be used for the secondary requests as shown in Table 3–1.

Table 3–1. Least-Significant-Bit Control Function

CONTROL BIT D0	CONTROL BIT FUNCTION
0	No operation (no-op)
1	Secondary communication request

On the falling edge of the next \overline{FS} , D15 through D1 is input to DIN or D15 through D0 is output to DOUT. When a secondary communication request is made, \overline{FS} goes low for 32 FCLKs (see Fk divide register, Appendix A) after the beginning of the primary frame.

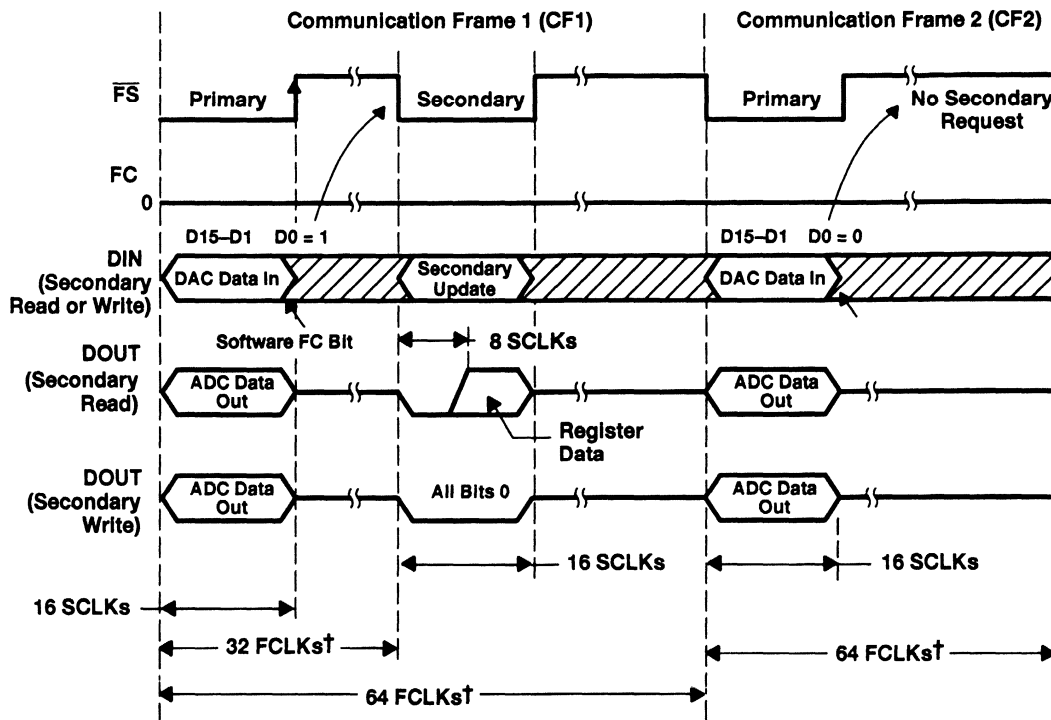


† See Fk divide register in Appendix A.

‡ For a selected MCLK, Fk and Fsclk: $SCLK = 2 Fk/Fsclk \times FCLK$

Figure 3–5. Hardware FC Secondary Request (Phone Mode Disabled)

In Figure 3–6, FC hardware terminal 15 is left in its nonasserted state (0). FC is asserted through software by embedding an asserted high level (1) in the LSB of the 16-bit primary word. This is possible when not in 16-bit mode (control 1 register bit 2 = 0) because the user is using only 15 bits of DAC information.



† See Fk divide register in Appendix A.

NOTE A: For a read cycle, the last 8 bits are don't care.

Figure 3–6. Software FC Secondary Request (Phone Mode Disabled)

Table 3–2 shows the secondary communications format. D13 is the R/W bit, the read/not-write bit.

D12 through D8 are address bits. The register map is specified in the register set section in Appendix A. D7 through D0 are data bits. The data bits are values for the specified register addressed by data bits D12 through D8.

Table 3–2. Secondary Communication Data Format

D15	D14	D13	D12	D11	D10	D9	D8	D7	D6	D5	D4	D3	D2	D1	D0
X	X	R/W	A	A	A	A	A	D	D	D	D	D	D	D	D

3.3 Conversion Rate Versus Serial Port

The SCLK frequency can be programmed independently from the FCLK frequency. This can create a problem with the interpretation of the serial port data. The serial port is designed to initiate a primary communication every 64 SCLKs. There must be an integer number of SCLKs ≥ 40 per sample period. Two examples follow to demonstrate the possible output of the serial port. SCLK must be fast enough to collect all data from each frame.

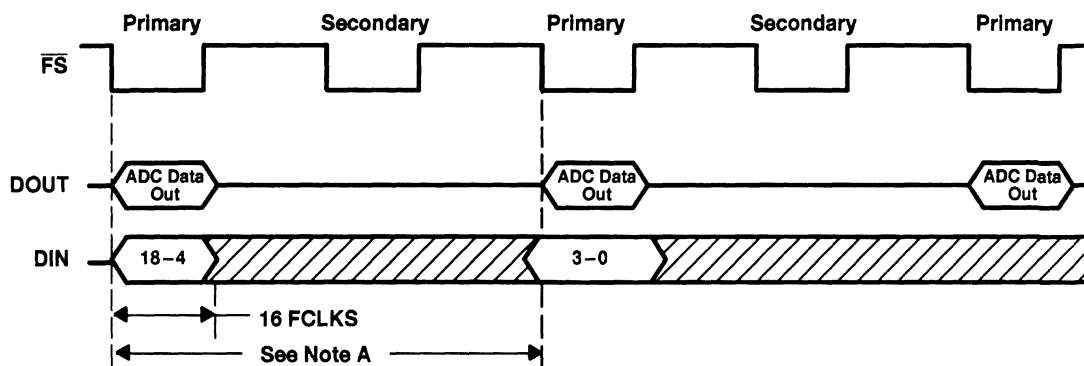
Example 1: MCLK = 4.096 MHz, sample rate = 8 kHz, $8 \text{ kHz} = \text{MCLK}/(\text{Fk} \times 256)$, set $\text{Fk} = 2$, $\text{SCLK} = \text{MCLK}/(\text{Fsclk} \times 2)$, set $\text{Fsclk} = 2$, $\text{SCLK} = 1.024 \text{ MHz}$. With this configuration, $\text{SCLK} = \text{sample rate} \times 128$. Therefore, each primary communication is a valid sample.

Example 2: All variables above remain the same except $F_{sclk} = 1$, $SCLK = 2.048 \text{ MHz} = \text{sample rate} \times 256$. In this configuration, two consecutive primary communications represent the same data sample.

3.4 FIR Bypass Mode

An option is provided to bypass the FIR sections of the decimation filter and the interpolation filter. This is selected through the control 2 register. The sinc filters of the two paths cannot be bypassed.

The timing requirements for this mode of operation are shown in Figure 3–7.



NOTE A: The number of clocks between primary cycles is a function of FCLK. When either FIR is bypassed, this period is 16 FCLKs. See Fk divide register in Appendix A.

Figure 3–7. FIR Bypass Timing

3.5 Phone Mode Control

This function is provided for applications that need hardware control and monitor of external events. By allowing the device to drive two FLAG terminals (set through the control 2 register), the host digital signal processor (DSP) is capable of system control through the same serial port connection to the device. Along with this control is the capability for monitoring the value of the ALT DATA terminal during a secondary communication cycle. One application for this function is in monitoring ring detect or offhook detect from a phone answering system. The two FLAG terminals allow response to these incoming control signals. Figure 3-8 shows the timing associated with this operating mode.

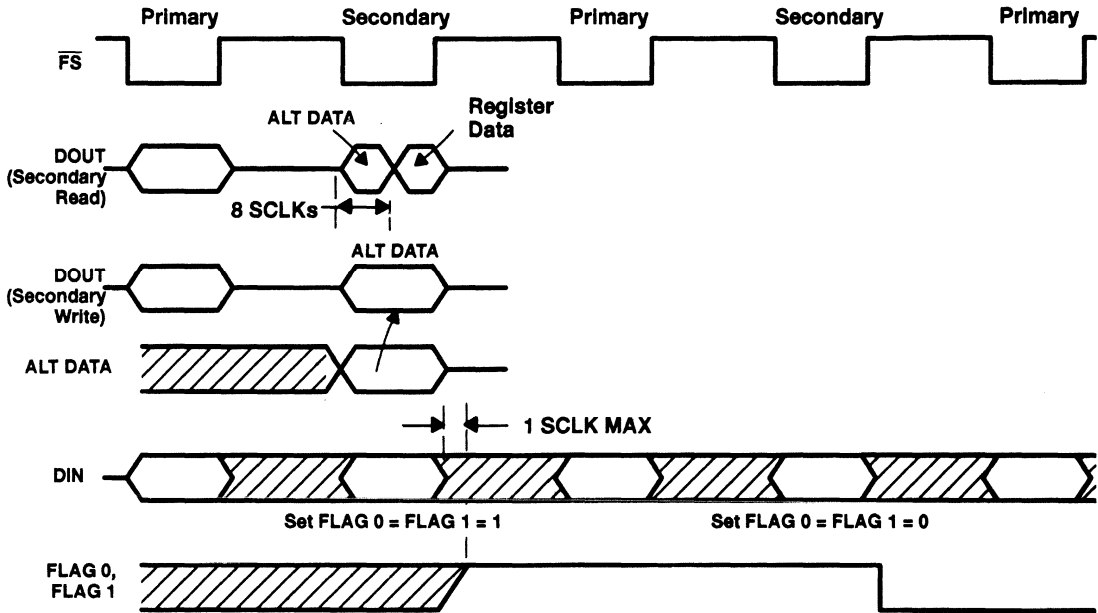


Figure 3-8. Phone Mode Timing

4 Specifications

4.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (unless otherwise noted)[†]

Supply voltage range, DV_{DD} , V_{DD} (ADC, DAC)(see Note 1)	-0.3 V to 6.5 V
Output voltage range, $DOUT$, \overline{FS} , $SCLK$, $FLAG_0$, $FLAG_1$...	-0.3 V to $DV_{DD} + 0.3$ V
Output voltage range, $OUTP$, $OUTM$	-0.3 V to $V_{DD} + 0.3$ V
Input voltage range, DIN , \overline{PWRDWN} , \overline{RESET} , $ALT\ DATA$, MCLK, FC	-0.3 V to $DV_{DD} + 0.3$ V
Input voltage range, INP , INM , $AUXP$, $AUXM$	-0.3 V to $V_{DD} + 0.3$ V
Case temperature for 10 seconds, T_C : DW package	260°C
Operating free-air temperature range, T_A	0°C to 70°C
Storage temperature range, T_{stg}	-65°C to 150°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to V_{SS} (DAC) for DAC channel measurements and V_{SS} (ADC) for ADC channel measurements.

4.2 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Supply voltage, V_{DD} (ADC, DAC)	4.5		5.5	V
Analog signal input voltage, V_I			6	V
	Differential, (INP–INM) peak, for full scale operation			
Load resistance for $OUTP$ and $OUTM$, R_L	0.3	10		k Ω
Load capacitance for $OUTP$ and $OUTM$, C_L			100	pF
ADC or DAC conversion rate (Nyquist)		8		kHz
Operating free-air temperature, T_A	0		70	°C

4.3 Recommended Operating Conditions, $DV_{DD} = 5$ V

	MIN	NOM	MAX	UNIT
Supply voltage, DV_{DD}	4.5		5.5	V
High-level input voltage, V_{IH}	2			V
Low-level input voltage, V_{IL}			0.8	V
MCLK frequency (see Note 2), duty cycle = 50 \pm 10%		16.384		MHz

NOTE 2: The default state for an 8 kHz conversion rate requires a 16.384 MHz MCLK frequency.

4.4 Electrical Characteristics, $T_A = 25^\circ\text{C}$, $V_{DD}(\text{ADC}) = V_{DD}(\text{DAC}) = DV_{DD} = 5\text{ V}$, $\text{MCLK} = 16.384\text{ MHz}$, $F_k = 8$ (unless otherwise noted)

4.4.1 Digital Inputs and Outputs, Outputs Not Loaded

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{OH}	High-level output voltage, DOUT	$I_O = 360\ \mu\text{A}$	2.4	4.6		V
V_{OL}	Low-level output voltage, DOUT	$I_O = 2\ \text{mA}$		0.2	0.4	V
I_{IH}	High-level input current, any digital input	$V_{IH} = 5\ \text{V}$			10	μA
I_{IL}	Low-level input current, any digital input	$V_{IL} = 0.8\ \text{V}$			10	μA
C_i	Input capacitance			5		pF
C_o	Output capacitance			5		pF

4.4.2 ADC Path Filter (see Note 3)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Filter gain relative to gain at 1020 Hz		20 Hz	-0.5	-0.15	0.2	dB
		200 Hz	-0.5	0.03	0.15	
		300 Hz to 3 kHz	-0.15	0	0.15	
		3.3 kHz	-0.35	-0.5	0.3	
		3.4 kHz	-1	-0.6	-0.1	
		4 kHz		-20	-14	
		$\geq 4.6\ \text{kHz}$			-40	

NOTE 3: The filter gain outside of the passband is measured with respect to the gain at 1020 Hz. The analog input test signal is a sine wave with 0 dB = 6 $V_I(\text{PP})$ as the reference level for the analog input signal. The passband is 0 to 3400 Hz.

4.4.3 ADC Dynamic Performance

4.4.3.1 ADC Signal-to-Noise (see Note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Signal-to-noise ratio (SNR)		$V_I = -1\ \text{dB}$	80	85		dB
		$V_I = -9\ \text{dB}$	72	77		
		$V_I = -40\ \text{dB}$	40	45		
		$V_I = -65\ \text{dB}$	14	21		
		$V_I(\text{AUXM}, \text{AUXP}) = -9\ \text{dB}$	72	78		

NOTE 4: The test condition is the digital equivalent of a 1020 Hz input signal with an 8 kHz conversion rate. The load impedance is 600 Ω . Input and output voltages are referred to $V_{DD}/2$.

4.4.3.2 ADC Signal-to-Distortion (see Note 4)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
Signal-to-total harmonic distortion (THD)		$V_I = -1\ \text{dB}$	80	92		dB
		$V_I = -9\ \text{dB}$	80	94		
		$V_I = -40\ \text{dB}$	40	60		
		$V_I = -65\ \text{dB}$	15	40		
		$V_I(\text{AUXM}, \text{AUXP}) = -9\ \text{dB}$	80	92		

NOTE 4: The test condition is the digital equivalent of a 1020 Hz input signal with an 8 kHz conversion rate. The load impedance is 600 Ω . Input and output voltages are referred to $V_{DD}/2$.

4.4.3.3 ADC Signal-to-Distortion+Noise (see Note 5)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Total harmonic distortion+noise (THD+N)	$V_I = -9$ dB	80	83		dB
	$V_I = -1$ dB	72	76		
	$V_I = -40$ dB	40	45		
	$V_I = -65$ dB	14	20		
	$V_I(\text{AUXM, AUXP}) = -9$ dB	72	77		

NOTE 5: The test condition is a 1020 Hz input signal with an 8 kHz conversion rate. Input and output voltages are referred to $V_{DD}/2$.

4.4.4 ADC Channel

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Dynamic range			86		dB
Interchannel isolation		80			dB
Gain error	$V_I = -1$ dB at 1020 Hz			± 0.5	dB
Gain error, dc	INP = 3 V, INM = 2 V		± 0.6		dB
Off-set error, ADC converter			8		mV
CMRR Common-mode rejection ratio INM, INP or AUXM, AUXP	$V_I = 0$ dB at 1020 kHz	80			dB
Idle channel noise (on-chip reference)				50	$\mu\text{V rms}$
R_i Input resistance	$T_A = 25^\circ\text{C}$	70	100		$\text{k}\Omega$

4.4.5 DAC Path Filter (see Note 6)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Filter gain relative to gain at 1020 Hz	20 Hz	-0.5	0.08	0.15	dB
	200 Hz	-0.5	0.08	0.15	
	300 Hz to 3 kHz	-0.15	0.08	0.15	
	3.3 kHz	-0.35	0.11	0.3	
	3.4 kHz	-1	-0.48	-0.1	
	4 kHz		-20	-14	
	≥ 4.6 kHz			-40	

NOTE 6: The filter gain outside of the passband is measured with respect to the gain at 1020 Hz. The input signal is the digital equivalent of a sine wave (digital full scale = 0 dB). The nominal differential DAC channel peak-to-peak output voltage with this input condition is 6 V. The pass band is 0 to 3600 Hz.

4.4.6 DAC Dynamic Performance

4.4.6.1 DAC Signal-to-Noise (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Signal-to-noise ratio (SNR)	$V_O = 0$ dB	74	80		dB
	$V_O = -9$ dB	70	74		
	$V_O = -40$ dB	38	44		
	$V_O = -65$ dB	14	18		

NOTE 4: The test condition is the digital equivalent of a 1020 Hz input signal with an 8 kHz conversion rate. The load impedance is 600 Ω . Input and output voltages are referred to $V_{DD}/2$.

4.4.6.2 DAC Signal-to-Distortion (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Signal-to-total harmonic distortion (THD)	$V_O = 0$ dB	74	84		dB
	$V_O = -9$ dB	74	84		
	$V_O = -40$ dB	40	58		
	$V_O = -65$ dB	18	30		

NOTE 4: The test condition is the digital equivalent of a 1020 Hz input signal with an 8 kHz conversion rate. The load impedance is 600 Ω . Input and output voltages are referred to $V_{DD}/2$.

4.4.6.3 DAC Signal-to-Distortion + Noise (see Note 4)

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Total harmonic distortion+noise (THD+N)	$V_O = 0$ dB	72	78		dB
	$V_O = -9$ dB	68	74		
	$V_O = -40$ dB	38	44		
	$V_O = -65$ dB	14	20		

NOTE 4: The test condition is the digital equivalent of a 1020 Hz input signal with an 8 kHz conversion rate. The load impedance is 600 Ω . Input and output voltages are referred to $V_{DD}/2$.

4.4.7 DAC Channel

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Dynamic range			80		dB
Interchannel isolation		80			dB
Gain error, 0 dB	$V_O = 0$ dB at 1020 Hz			± 0.5	dB
Gain error, dc	Digital input offset = 1 V dc		± 0.2		dB
Idle channel broad-band noise	See Note 7			100	μ V rms
Idle channel narrow-band noise	0 – 4 kHz, See Note 7			40	μ V rms
V_{OO} Output offset voltage at OUT (differential)	DIN = All 0s		8		mV
V_O Analog output voltage, peak-to-peak, OUTP – OUTM (differential)	$R_L = 600$, With internal reference and full-scale digital input, (see Note 8)			6	V

NOTES: 7. The conversion rate is 8 kHz; the out-of-band measurement is made from 4800 Hz to $F_{MCLK}/2$.

8. The digital input to the DAC channel at DIN is in 2s complement.

4.4.8 Power Supplies, $V_{DD}(ADC) = V_{DD}(DAC) = DV_{DD} = 5\text{ V}$, No Load (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
I_{DD} (ADC)	Power supply current, ADC	Operating		12	20	mA
		Power-down		400		μA
I_{DD} (DAC)	Power supply current, DAC	Operating		16	24	mA
		Power-down		2.5		mA
I_{DD} (Digital)	Power supply current, digital	Operating		2	6	mA
		Power-down		300		μA
P_D	Power dissipation	Operating		150	250	mW
		Power-down		16	30	

4.4.9 Timing Requirements (see Notes 9 and 10)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
t_{d1}	Delay time, SCLK \uparrow to $\overline{FS}\downarrow$	$C_L = 20\text{ pF}$		10	15	ns
t_{d2}	Delay time, SCLK \uparrow to DOUT			6	20	
t_{su}	Setup time, DIN before SCLK \downarrow			20		
t_h	Hold time, DIN after SCLK \downarrow				20	
t_{en}	Enable time, $\overline{FS}\downarrow$ to DOUT			10	25	
t_{dis}	Disable time, $\overline{FS}\uparrow$ to DOUT Hi-Z			20		
t_{d3}	Delay time MCLK \downarrow to SCLK \uparrow			25	50	

- NOTES: 9. Refer to Figure 3–1 for timing diagram.
 10. When \overline{FS} occurs after SCLK, it shortens the MSB (D15) duration.

5 Application Information

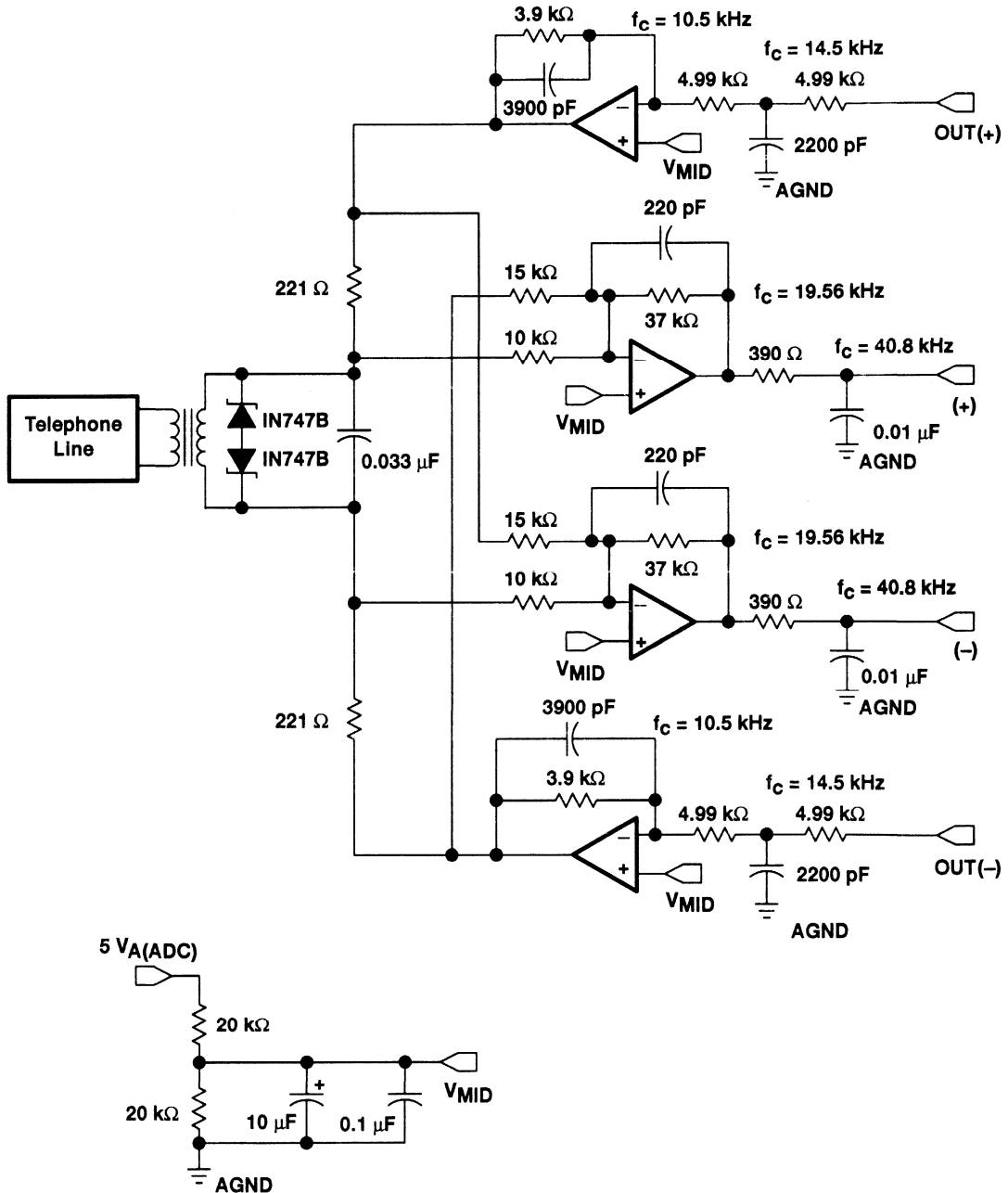


Figure 5-1. TLC320AD55C Application Schematic

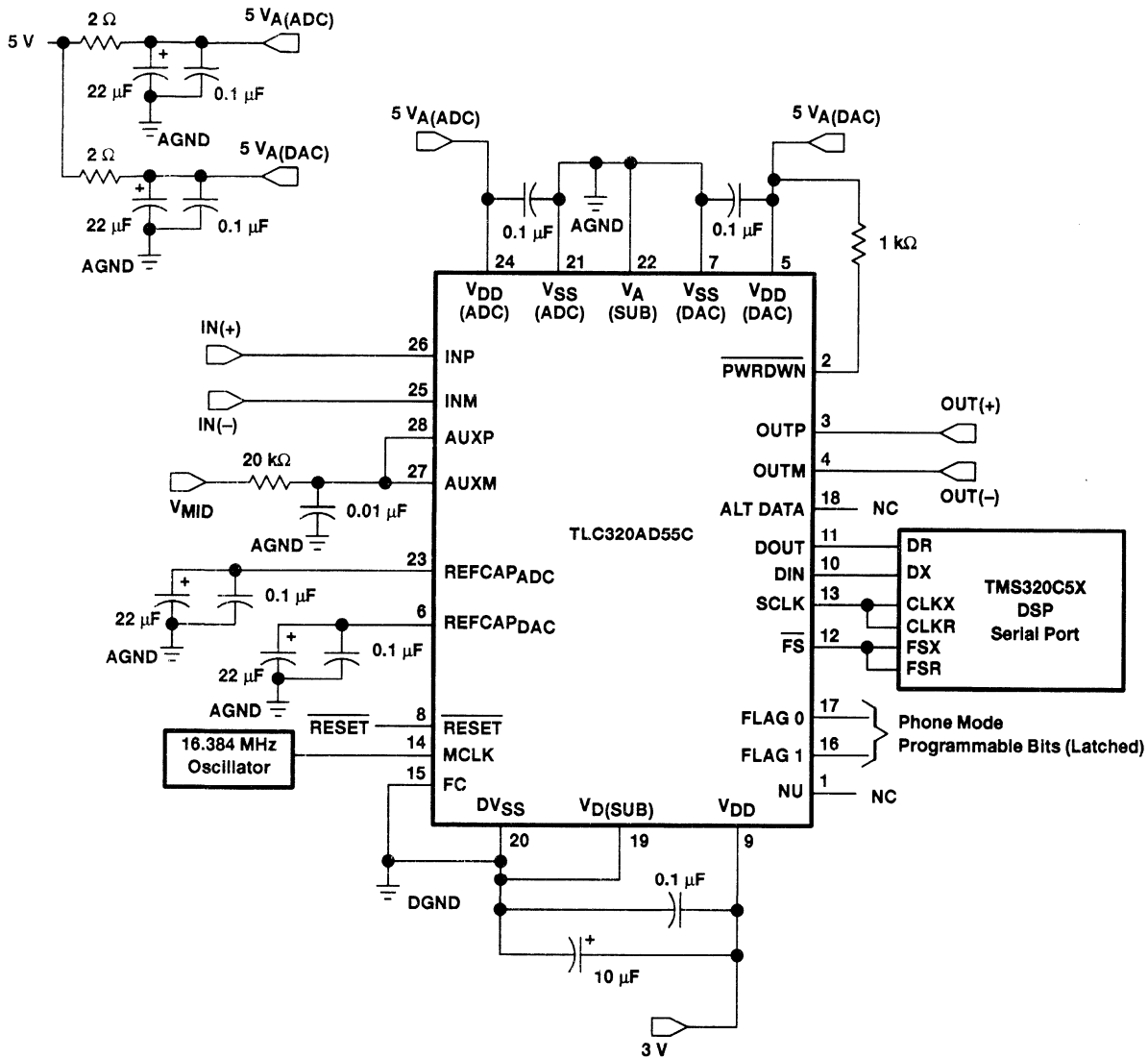


Figure 5-2. TLC320AD55C I/O Buffer and V_{MID} Generator Schematic

Appendix A Register Set

Data bits D12 through D8 in the secondary serial communication contain the address of the register, and data bits D7 through D0 contain the data that is to be written to the register. Data bit D13 determines a read or write cycle to the addressed register. When data bit D13 is low, a write cycle is selected.

The following table shows the register map:

Table A–1. Register Map

REGISTER NO.	D15	D14	D13	D12	D11	D10	D9	D8	REGISTER NAME
0	0	0	0	0	0	0	0	0	No operation
1	0	0	0	0	0	0	0	1	Control 1
2	0	0	0	0	0	0	1	0	Control 2
3	0	0	0	0	0	0	1	1	Fk divide
4	0	0	0	0	0	1	0	0	Fsclk divide
5	0	0	0	0	0	1	0	1	Control 3

Table A–2. Control 1 Register

D7	D6	D5	D4	D3	D2	D1	D0	DESCRIPTION
1	–	–	–	–	–	–	–	Software reset
0	–	–	–	–	–	–	–	Software reset not asserted
–	1	–	–	–	–	–	–	Software power down (analog and filters)
–	0	–	–	–	–	–	–	Software power down (not asserted)
–	–	1	–	–	–	–	–	Select AUXP and AUXM
–	–	0	–	–	–	–	–	Select INP and INM
–	–	–	0	0	–	–	–	Analog output gain = 1
–	–	–	0	1	–	–	–	Analog output gain = 1/2
–	–	–	1	0	–	–	–	Analog output gain = 1/4
–	–	–	1	1	–	–	–	Analog output gain = 0 (squench)
–	–	–	–	–	1	–	–	Analog loopback asserted
–	–	–	–	–	0	–	–	Analog loopback not asserted
–	–	–	–	–	–	1	–	Digital loopback asserted
–	–	–	–	–	–	0	–	Digital loopback not asserted
–	–	–	–	–	–	–	1	16-bit mode (hardware secondary requests)
–	–	–	–	–	–	–	0	Not 16-bit mode (software secondary requests)

Default register value: 00000000

The software reset is a one-shot operation and this bit is cleared to zero after reset. It is not necessary to write a zero to end the master reset operation.

Table A–3. Control 2 Register

D7	D6	D5	D4	D3	D2	D1	D0	DESCRIPTION
X	X	–	–	–	–	–	–	Reserved
–	–	X	–	–	–	–	–	Decimator FIR overflow flag (valid only during read cycle)
–	–	–	X	–	–	–	–	FLAG 1 output value
–	–	–	–	X	–	–	–	FLAG 0 output value
–	–	–	–	–	1	–	–	Phone mode enabled
–	–	–	–	–	0	–	–	Phone mode disabled
–	–	–	–	–	–	0	–	Normal operation with decimator FIR filter
–	–	–	–	–	–	1	–	Bypass decimator FIR filter
–	–	–	–	–	–	–	0	Normal operation with interpolator filter
–	–	–	–	–	–	–	1	Bypass interpolator FIR filter

Default register value: 00000000

Writing zeros to the reserved bits is suggested.

Table A–4. Fk Divide Register

D7	D6	D5	D4	D3	D2	D1	D0	DIVIDE VALUE
1	1	1	1	1	1	1	1	255
			•			•		
			•			•		
1	0	0	0	0	0	0	0	128
			•			•		
			•			•		
0	0	1	0	0	0	0	0	32
			•			•		
			•			•		
0	0	0	0	0	0	0	1	1
0	0	0	0	0	0	0	0	256

Default register value: 00001000

The oversampling clock (FCLK) is set as $MCLK/(Fk \times 4)$. $MCLK/(Fk \times 256)$ is the sample frequency (conversion rate) for the converter. When Fk is programmed to zero, its value is interpreted as 256.

Table A–5. FscIk Divide Register

D7	D6	D5	D4	D3	D2	D1	D0	DIVIDE VALUE
1	1	1	1	1	1	1	1	255
		•				•		
		•				•		
		•				•		
1	0	0	0	0	0	0	0	128
		•				•		
		•				•		
		•				•		
0	0	1	0	0	0	0	0	32
		•				•		
		•				•		
		•				•		
0	0	0	0	0	0	0	1	1
0	0	0	0	0	0	0	0	256

Default register value: 00001000

SCLK is set by $MCLK/(2 \times FscIk)$. SCLK is for the serial transfer of data to and from the TLC320AD55C. When FscIk is programmed to zero, its value is interpreted as 256.

Table A–6. Control 3 Register

D7	D6	D5	D4	D3	D2	D1	D0	DESCRIPTION
0	0	0	0	1	0	0	0	DAC reference disabled
0	0	0	0	0	0	0	0	DAC reference enabled

TLC320AD57C ***Data Manual***

Sigma-Delta Stereo Analog-to-Digital Converter



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1 Introduction

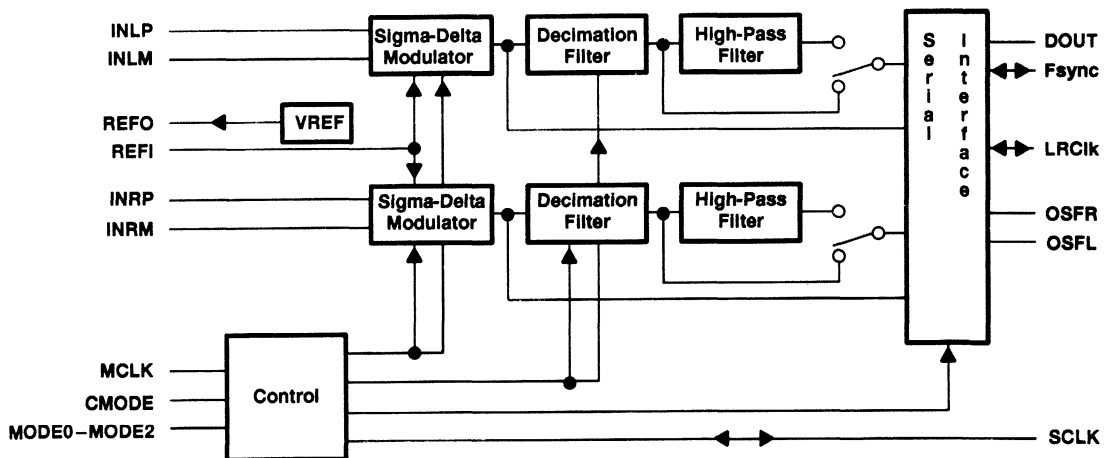
The TLC320AD57C provides high-resolution signal conversion from analog to digital using oversampling sigma-delta technology. This device consists of two synchronous conversion paths. Also included is a decimation filter after the modulator as shown in the functional block diagram. Other functions provide analog filtering and on-chip timing and control.

A functional block diagram of the TLC320AD57C is included in section 1.2. Each block is described in the Detailed Description section.

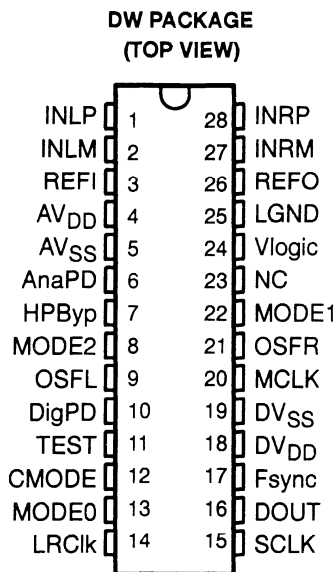
1.1 Features

- Single 5-V Power Supply
- Sample Rates (f_s) up to 48 kHz
- 18-Bit Resolution
- Signal-to-Noise (EIAJ) of 97 dB
- Dynamic Range of 95 dB
- Total Signal-to-Noise+Distortion of 91 dB
- Internal Reference Voltage (V_{ref})
- Serial Port Interface
- Differential Architecture
- Power Dissipation of 200 mW. Power-Down Mode for Low-Power Applications
- One Micron Advanced LinEPIC1Z™ Process

1.2 Functional Block Diagram



1.3 Terminal Assignments



NC – No internal connection

1.4 Ordering Information

TA	PACKAGE
	SMALL OUTLINE (DW)
0°C to 70°C	TLC320AD57CDW

1.5 Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AnaPD	6	I	Analog power-down mode. The analog power-down mode disables the analog modulators. The single-bit modulator outputs become invalid, which renders the outputs of the digital filters invalid. When AnaPD is pulled low, normal operation of the device resumes.
AV _{DD}	4	I	Analog supply voltage
AV _{SS}	5	I	Analog ground
CMODE	12	I	Clock mode. CMODE selects between two methods of determining the master clock frequency. When CMODE is high, the master clock input is 384x the conversion frequency. When CMODE is low, the master clock input is 256x the conversion frequency.
DOUT	16	O	Data output. DOUT transmits the sigma-delta audio analog-to-digital converter (ADC) output data to a digital signal processor (DSP) serial port or other compatible serial interface and is synchronized to SCLK. DOUT is low when DigPD is high.
DV _{DD}	18	I	Digital supply voltage

1.5 Terminal Functions (Continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION																																				
DVSS	19	I	Digital ground																																				
DigPD	10	I	Digital power-down mode. The digital power-down mode shuts down the digital filters and clock generators. All digital outputs are brought to unasserted levels. When DigPD is pulled low, normal operation of the device resumes.																																				
Fsync	17	I/O	Frame synchronization. Fsync designates valid data from the ADC.																																				
HPByP	7	I	High-pass filter bypass. When HPByP is high, the high-pass filter is bypassed. This allows dc analog signal conversion.																																				
INLM	2	I	Inverting input to left analog input amplifier																																				
INLP	1	I	Noninverting input to left analog input amplifier																																				
INRM	27	I	Inverting input to right analog input amplifier																																				
INRP	28	I	Noninverting input to right analog input amplifier																																				
LGND	25	I	Logic-power-supply ground for analog modulator																																				
LRCIk	14	I/O	Left/right clock. LRCIk signifies whether the serial data is associated with the left channel ADC (when high) or the right channel ADC (when low). LRCIk is low when DigPD is high.																																				
MCLK	20	I	Master clock. MCLK derives all of the key logic signals of the sigma-delta audio ADC. The nominal input frequency range is 18.432 MHz to 256 kHz.																																				
MODE0–MODE2	8, 13, 22	I	<p>Serial modes. MODE0–MODE2 configure this device for many different modes of operation. The different configurations are:</p> <ul style="list-style-type: none"> Master versus slave 16 bit versus 18 bit MSB first versus LSB first Slave: Fsync controlled versus Fsync high <p>Each of these modes is described in the Serial Interface section with timing diagrams.</p> <table border="1" style="margin-left: auto; margin-right: auto;"> <thead> <tr> <th>MODE</th> <th>MASTER/ SLAVE</th> <th>BITS</th> <th>MSB/LSB FIRST</th> </tr> </thead> <tbody> <tr> <td>0 0 0</td> <td>slave</td> <td>up to 18</td> <td>MSB</td> </tr> <tr> <td>0 0 1</td> <td>slave</td> <td>18</td> <td>LSB</td> </tr> <tr> <td>0 1 0</td> <td>slave</td> <td>up to 18</td> <td>MSB</td> </tr> <tr> <td>0 1 1</td> <td>master</td> <td>16</td> <td>MSB</td> </tr> <tr> <td>1 0 0</td> <td>master</td> <td>18</td> <td>MSB</td> </tr> <tr> <td>1 0 1</td> <td>master</td> <td>18</td> <td>LSB</td> </tr> <tr> <td>1 1 0</td> <td>master</td> <td>16</td> <td>MSB</td> </tr> <tr> <td>1 1 1</td> <td>master</td> <td>16</td> <td>LSB</td> </tr> </tbody> </table>	MODE	MASTER/ SLAVE	BITS	MSB/LSB FIRST	0 0 0	slave	up to 18	MSB	0 0 1	slave	18	LSB	0 1 0	slave	up to 18	MSB	0 1 1	master	16	MSB	1 0 0	master	18	MSB	1 0 1	master	18	LSB	1 1 0	master	16	MSB	1 1 1	master	16	LSB
MODE	MASTER/ SLAVE	BITS	MSB/LSB FIRST																																				
0 0 0	slave	up to 18	MSB																																				
0 0 1	slave	18	LSB																																				
0 1 0	slave	up to 18	MSB																																				
0 1 1	master	16	MSB																																				
1 0 0	master	18	MSB																																				
1 0 1	master	18	LSB																																				
1 1 0	master	16	MSB																																				
1 1 1	master	16	LSB																																				
OSFL, OSFR	9, 21	O	Over scale flag left/right. If the left/right channel analog input exceeds the full scale input range for two consecutive conversions, OSFL and OSFR are set high for 4096 LRCIk periods. OSFL and OSFR are low when DigPD is high.																																				
SCLK	15	I/O	Shift clock. If SCLK is configured as an input, SCLK clocks serial data out of the sigma-delta audio ADC. If SCLK is configured as an output, SCLK stops clocking when DigPD is high.																																				
TEST	11	I	Test mode. TEST should be low for normal operation.																																				
REFI	3	I	Input voltage for modulator reference (normally connected to REFO, terminal 26).																																				
REFO	26	I	Internal voltage reference																																				
Vlogic	24	I	Logic power supply (5 V) for analog modulator																																				

2 Detailed Description

The following sections contain a detailed description of the TLC320AD57C.

2.1 Power-Down and Reset Functions

The following sections contain descriptions of the power-down and reset functions of the TLC320AD57C.

2.1.1 Power Down

The power-down state is comprised of a separate digital and analog power down. The power consumption of each is detailed in Section 3.3, Electrical Characteristics.

The digital power-down mode shuts down the digital filters and clock generators. All digital outputs are set to an unasserted level. When the digital power-down terminal (DigPD) is pulled low, normal operation of the device is initiated.

In slave mode, the conversion process must synchronize to an input on the LRCIk terminal and the SCLK terminal. Therefore, the conversion process is not initiated until the first rising edges on both SCLK and LRCIk are detected after DigPD is pulled low. This synchronizes the conversion cycle. All conversions are performed at a fixed LRCIk rate [MCLK/256 (CMODE low) or MCLK/384 (CMODE high)] after the initial synchronization. After the digital power-down terminal is brought low, the output of the digital filters remains invalid for 50 LRCIk cycles [see Figures 2–1(a) and 2–1(b)].

In master mode, LRCIk is an output; therefore, the conversion process initiates based on internal timing. The first valid data out occurs as shown in Figure 2–1(c).

The analog power-down mode disables the analog modulators. The single-bit modulator outputs become invalid, which renders the outputs of the digital filters invalid. When the analog power-down terminal is brought low, the modulators are brought back online; however, the outputs of the digital filters require 50 LRCIk cycles for valid results.

2.1.2 Reset Function

The conversion process is not initiated until the first rising edges on both SCLK and LRCIk are detected after DigPD is pulled low. This synchronizes the conversion cycle. All conversions are performed at a fixed LRCIk rate [$MCLK/256$ (CMODE low) or $MCLK/384$ (CMODE high)] after the initial synchronization.

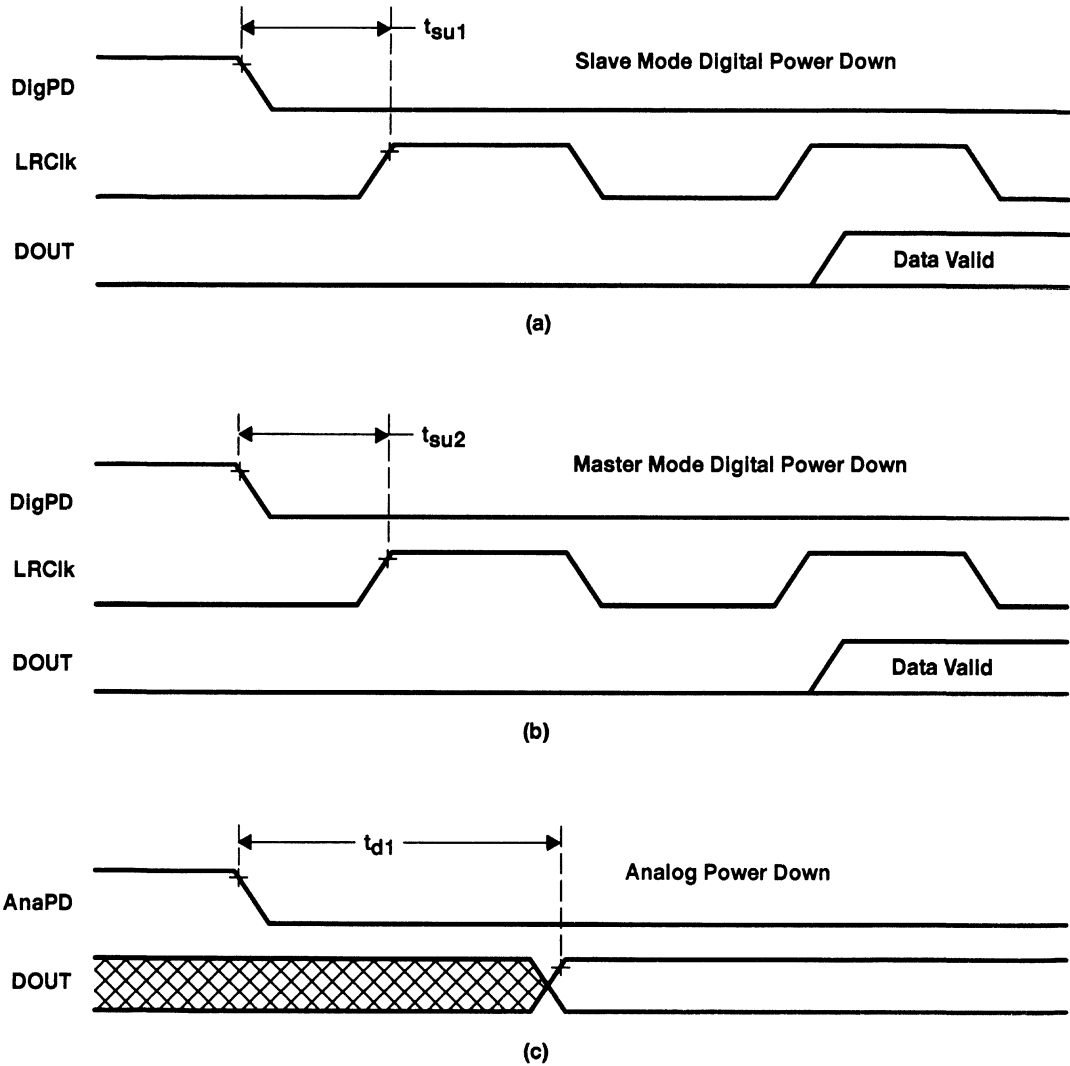


Figure 2–1. Power-Down Timing Relationships

2.2 Differential Input

The input is differential in order to provide common-mode noise rejection and increase the input dynamic range. Figure 2–2 shows the analog input signals used in a differential configuration to achieve 6.4-V peak-to-peak differential swing with a 3.2-V peak-to-peak swing per input line.

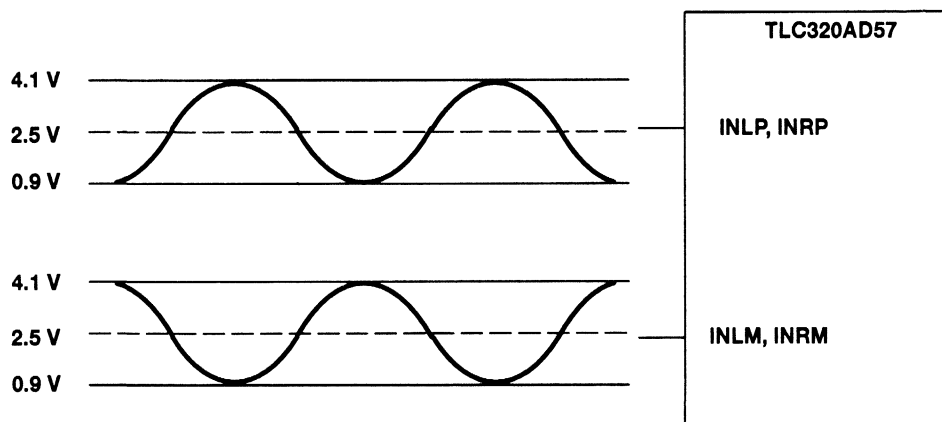


Figure 2–2. Differential Analog Input Configuration

2.3 Sigma-Delta Modulator

The modulator is a fourth order sigma-delta modulator with 64 times oversampling. The ADC provides high-resolution, low-noise performance from a one-bit converter using oversampling techniques.

2.4 Decimation Filter

The decimation filter used after the sigma-delta modulator reduces the digital data rate to the sampling rate of LRCIk. This is accomplished by decimating with a ratio of 1:64. The output of this filter is a 2s complement data word of up to 18 bits serially clocked out.

If the input value exceeds the full range of the converter, the output of the decimator is held at the appropriate extreme until the input returns to within the dynamic range of the device.

2.5 High-Pass Filter

The high-pass filter removes dc from the input. With this filtering, offset calibration is not needed. The high-pass filter can be circumvented by asserting the HPByp terminal to pass dc signals through the converter. However, an offset due to the converter can be present when bypassing the high-pass filter.

2.6 Master-Clock Circuit

The master-clock circuit generates and distributes necessary clocks throughout the device. MCLK is the external master-clock input. CMODE selects the relationship of MCLK to the sample rate, LRCIk. When CMODE is low, the sample rate of the data paths is set to $LRCIk = MCLK/256$. When CMODE is high, the sample rate is set to $LRCIk = MCLK/384$. With a fixed oversampling ratio of 64x, the effect of changing MCLK is shown in Table 2–1.

When the device is in master mode, SCLK is derived from MCLK in order to provide clocking of the serial communications between the sigma-delta audio ADC and a digital signal processor (DSP) or control logic. This is equivalent to a clock running at $64 \times LRCIk$.

When the device is in slave mode, SCLK is externally derived.

**Table 2–1. Master-Clock to Sample-Rate Comparison
(modes 1, 3, 4, 5)**

MCLK (MHz)	CMODE	SCLK (MHz)	LRCIk (kHz)
12.2880	Low	3.0720	48
18.4320	High		
11.2896	Low	2.8224	44.1
16.9344	High		
8.1920	Low	2.0480	32
12.2880	High		
0.2560	Low	0.0640	1
0.3840	High		

2.7 Test

When the TEST input is high, the test mode is selected, which routes the high speed one-bit modulator result to the serial port output. When in the test mode, the SCLK output frequency is equal to the data output rate. LRCIk is an input when the test mode is selected. This allows for the selection of the left or right modulator output to be routed to the serial port (high = left and low = right).

2.8 Serial Interface

Although the serial data is shifted out in two separate time packets that represent the left and right channels, the inputs are sampled and converted simultaneously.

The serial interface protocol has master and slave modes each with different read-out modes. The master mode sources the control signals for conversion synchronization while the slave mode allows an external controller to provide conversion synchronization signals.

The five master modes are shown in Figures 2–3(a) through 2–3(e) and the three slave modes are shown in Figures 2–4(a) through 2–4(c). For a 16-bit word, D15 is the most significant bit and D0 is the least significant bit. Unless otherwise specified, all values are in 2s complement format.

In the master mode, SCLK is generated internally and is sourced as an output. The relationship of SCLK to LRCIk is 64× (modes 1, 3, 4, 5) or 32× (modes 6, 7). In the slave mode, SCLK is an input. SCLK timing must meet the timing specifications listed in the Recommended Operating Conditions section.

2.8.1 Master Mode

As the master, the TLC320AD57C generates LRCIk, Fsync, and SCLK from MCLK. These signals are provided for synchronizing the serial port of a DSP or other control devices.

Fsync designates valid data from the ADC, and accomplishes this in the master modes by one of two methods. The first method is to place a single pulse on Fsync prior to valid data. This indicates the starting point for the data. The second method of frame synchronization is to hold Fsync high during the entire valid data cycle which provides boundaries for the data.

LRCIk is generated internally from MCLK. The frequency of this signal is fixed at the sampling frequency f_s [MCLK/256 (CMODE low) or MCLK/384 (CMODE high)]. During the high period of this signal, the left channel data is serially shifted to the output; during the low period, the right channel data is shifted to the output. The conversion cycle synchronizes with the rising edge of LRCIk.

Five modes are available when the device is configured as a master. Two modes are for 18-bit communications. These modes differ from each other in that the MSB is transferred first in one mode while the LSB is transferred first in the second mode [see Figures 2–3(b) and 2–3(c)]. When the LSB is transferred first, the data is right justified to the LRCIk [see Figures 2–3(a) through 2–3(e)]. The three other modes

available as a master are 16-bit modes. Two of the modes differ as MSB first versus LSB first. These two modes set $SCLK = LRCIk \times 32$. This is one half the frequency used in the other transfer modes [see Figures 2-3(d) and 2-3(e)]. The third 16-bit mode provides the data MSB first with one clock delay after $LRCIk$ [see Figure 2-3(a)].

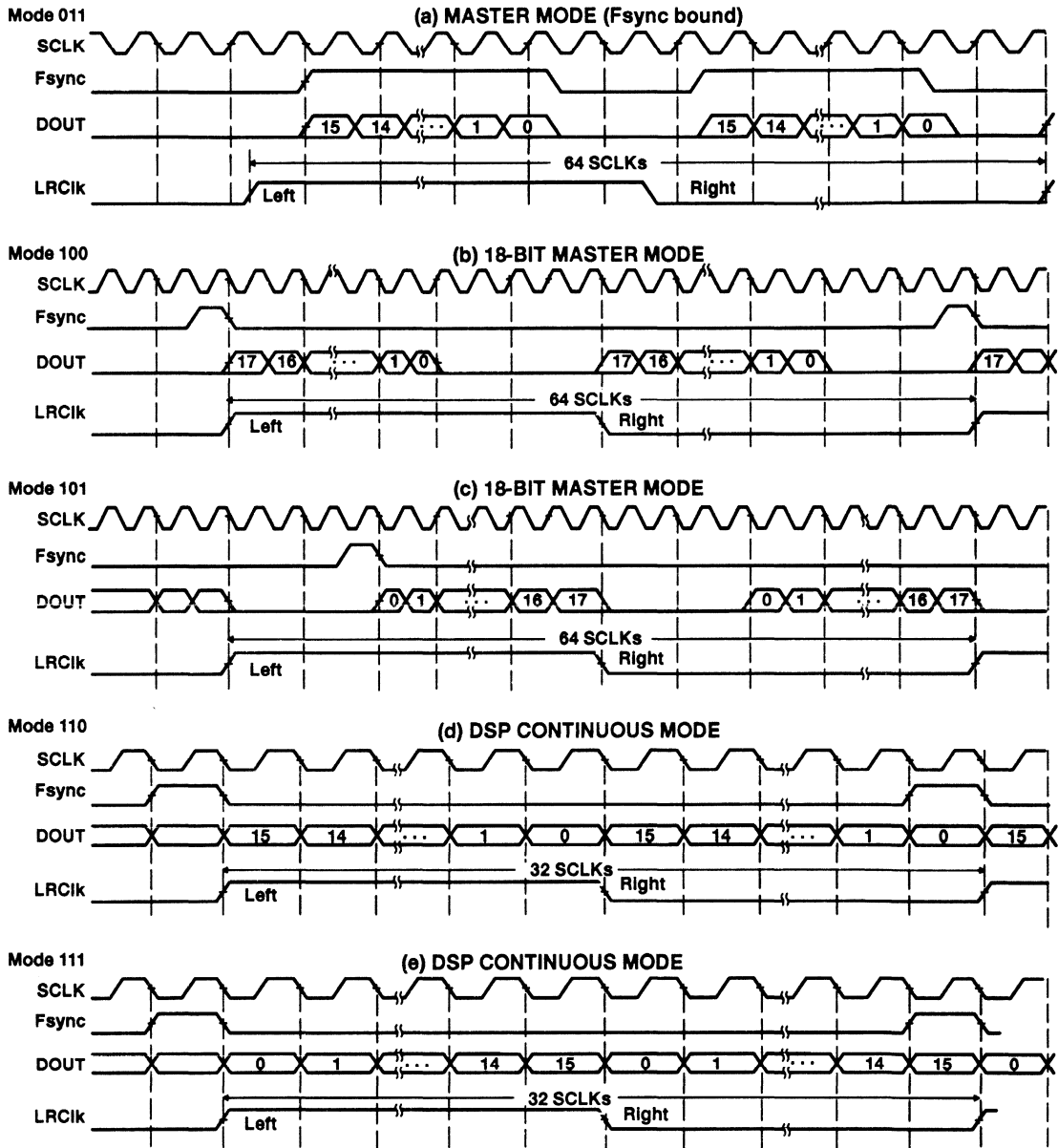


Figure 2-3. Serial Master Transfer Modes

2.8.2 Slave Mode

As a slave, the TLC320AD57C receives LRCIk, Fsync, and SCLK as inputs. The conversion cycle synchronizes to the rising edge of LRCIk, and the data synchronizes to the falling edge of SCLK. SCLK must meet the setup time requirements specified in Section 3.2, Recommended Operating Conditions. Synchronization of the slave modes is accomplished with the digital power-down control.

In slave mode, Fsync is an input. Three modes are provided as shown in Figures 2–4(a) through 2–4(c).

SCLK and LRCIk are externally generated and sourced. The first rising edges of SCLK and LRCIk after a power-down cycle initiate the conversion cycle. Refer to Section 2.8.1, Master Mode for signal functions.

Several modes are available when the TLC320AD57C is configured as a slave. Using the Mode0, Mode1, and Mode2 terminals, the TLC320AD57C can be set to shift out the MSB first or the LSB first [see Figures 2–4(a) and 2–4(b)]. The number of bits shifted out can be controlled by the number of valid SCLK cycles provided within the left or right channel period. If only enough clocks are provided to shift out 16 data bits before LRCIk changes state, this is equivalent to a 16-bit mode.

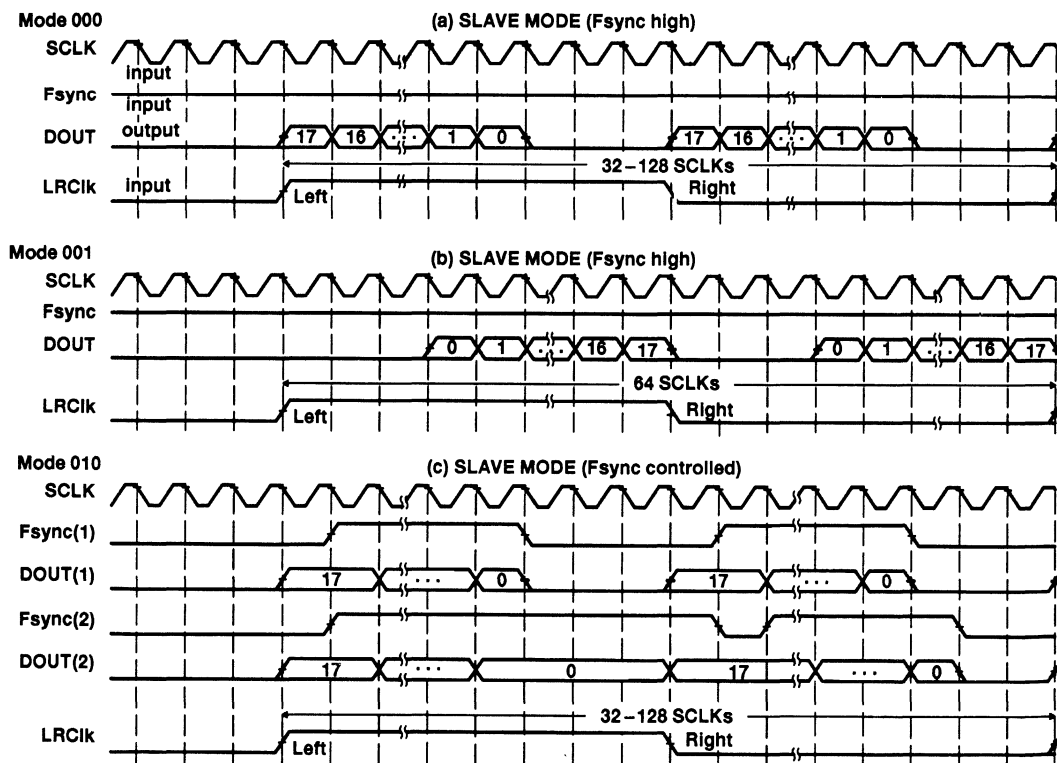


Figure 2–4. Serial Slave Transfer Modes

3 Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (Unless Otherwise Noted)[†]

Analog supply voltage range, AV _{DD} (see Note 1)	−0.3 V to 6.5 V
Digital supply voltage range, DV _{DD} (see Note 2)	−0.3 V to 6.5 V
Digital output voltage range, (externally applied)	−0.3 V to DV _{DD} + 0.3 V
Digital input voltage range, MODE0 – MODE2	−0.3 V to DV _{DD} + 0.3 V
Analog input voltage range, INLP, INLM, INRP, INRM	−0.3 V to AV _{DD} + 0.3 V
Operating free-air temperature range, T _A	0°C to 70°C
Storage temperature range, T _{stg}	−65°C to 150°C
Case temperature for 10 seconds, T _C	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES: 1. Voltage values for maximum ratings are with respect to AV_{SS}.
 2. Voltage values for maximum ratings are with respect to DV_{SS}.

3.2 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Analog supply voltage, AV _{DD} (see Note 3)	4.75	5	5.25	V
Digital supply voltage, DV _{DD}	4.75	5	5.25	V
Analog logic supply voltage, at V _{logic}	4.75	5	5.25	V
Reference voltage, V _{ref}		3.2		V
Setup time, DigPD↓ to LRCIk↑, slave mode, t _{su1} (see Figure 2–1(a))		30		ns
Setup time, DigPD↓ to LRCIk↑, master mode, t _{su2} (see Figure 2–1(b))		30		ns
Setup time, SCLK↑ to LRCIk, slave mode, t _{su3} (see Figures 4–5 and 4–6)	30			ns
Setup time, LRCIk to SCLK↑, slave mode, t _{su4} (see Figure 4–5)	30			ns
Setup time, SCLK↑ to Fsync, slave mode, t _{su5} (see Figure 4–6)	30			ns
Setup time, Fsync to SCLK↑, slave mode, t _{su6} (see Figure 4–6)	30			ns
Load resistance at DOUT, R _L		10		kΩ
Operating free-air temperature, T _A	0		70	°C

NOTE 3: Voltages at analog inputs and outputs and AV_{DD} are with respect to the AV_{SS} terminal.

3.3 Electrical Characteristics

3.3.1 Digital Interface, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IH} High-level input voltage		2	4.6		V
V_{IL} Low-level input voltage			0.2	0.8	V
V_{OH} High-level output voltage, DOUT	$I_{OH} = 2\text{ mA}$	2.4	4.6		V
V_{OL} Low-level output voltage, DOUT	$I_{OL} = 2\text{ mA}$		0.2	0.4	V
I_{IH} High-level input current, any digital input			1		μA
I_{IL} Low-level input current, any digital input			1		μA
C_i Input capacitance			5		pF
C_o Output capacitance			5		pF

3.3.2 Analog Interface

3.3.2.1 ADC Modulator, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$, $f_s = 48\text{ kHz}$, Bandwidth = 24 kHz, HPByp = 1, CMODE = 0, MODE0 – 2 = 101

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Resolution			18		Bits
DYNAMIC PERFORMANCE					
Signal to noise (EIAJ)	INLP = INRP = 2.5 V dc INLM = INRM = 2.5 V dc	93	97		dB
Dynamic range	-1dB down from 6-V differential input between INRP (INLP) and INRM (INLM)	91	95		dB
Signal to noise + distortion (THD + N)			91		dB
Total harmonic distortion (THD)			0.001%		
Interchannel isolation			108		dB
DC ACCURACY					
Gain error			± 0.2		dB
Interchannel gain mismatch			± 0.2		dB
Offset error (18-bit resolution)			± 5		mV
Offset drift			± 0.17		LSB/ $^\circ\text{C}$

3.3.2.2 Inputs/Supplies, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$, $f_s = 48\text{ kHz}$, Bandwidth = 24 kHz, HPByp = 1

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUT					
Input voltage	Differential input		6.4		V
	Single-ended input		3.2		
Input impedance			50		k Ω
POWER SUPPLIES					
Power-supply current	I _{DD} (analog), operating		22	30	mA
	I _{DD} (digital), operating		24	32	mA
	I _{DD} (analog), power down		100		μA
	I _{DD} (digital), power down		40		μA
Power dissipation			230		mW

3.3.3 Channel Characteristics, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$, $f_s = 48\text{ kHz}$, HPByp = 1

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Passband (-3 dB)	HPByp = 0	0.001		24	kHz
Passband ripple	30 Hz – 21.8 kHz		± 0.01		dB
Stopband attenuation	26.2 kHz – 3046 kHz	80			dB
Group delay			$25/F_s$		s

3.4 Switching Characteristics

PARAMETER	MIN	TYP	MAX	UNIT
t _{d1} Delay time, AnaPD↓ to DOUT valid (see Figure 2-1(c))		30		ns
t _d (MFSD) Delay time, SCLK↓ to Fsync, master mode (see Figures 4-1, 4-2, 4-3, and 4-4)	-20		20	ns
t _d (MDD) Delay time, SCLK↓ to DOUT, master mode (see Figures 4-1, 4-2, 4-3, and 4-4)	0		50	ns
t _d (MIRD) Delay time, SCLK↓ to LRCIk, master mode (see Figures 4-2 and 4-4)	-20		20	ns
t _d (SDD1) Delay time, LRCIk to DOUT, slave mode (see Figure 4-5)			50	ns
t _d (SDD2) Delay time, SCLK↓ to DOUT, slave mode (see Figures 4-5 and 4-6)			50	ns

4 Parameter Measurement Information

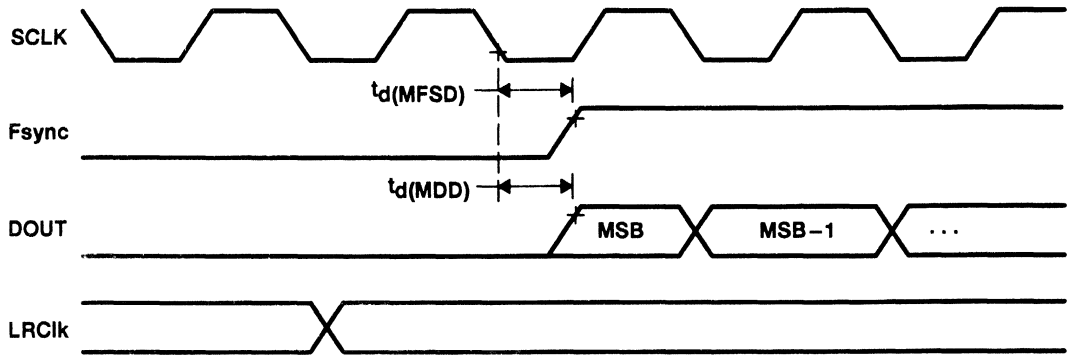


Figure 4-1. SCLK to Fsync and DOUT – Master Mode 3

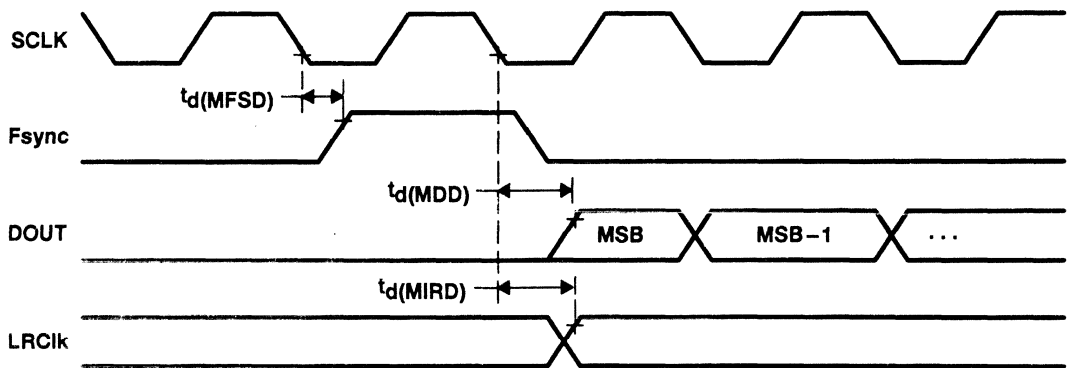


Figure 4-2. SCLK to Fsync, DOUT, and LRCIk – Master Modes 4 and 6

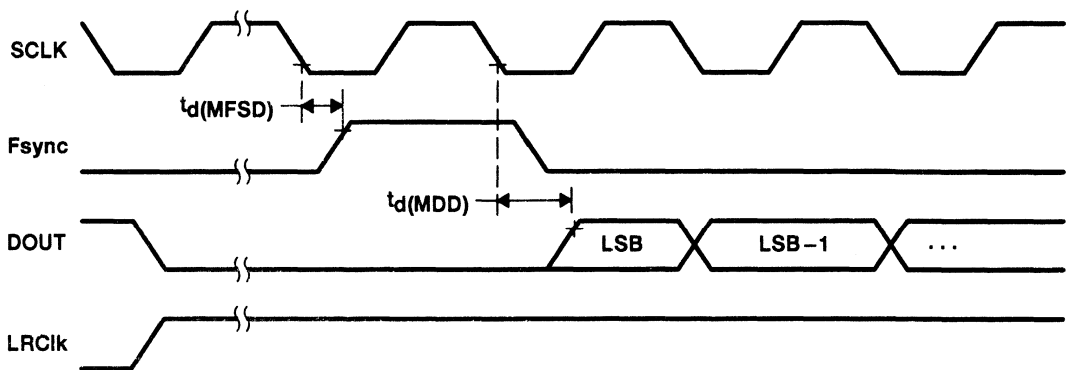


Figure 4-3. SCLK to Fsync, DOUT, and LRCIk – Master Mode 5

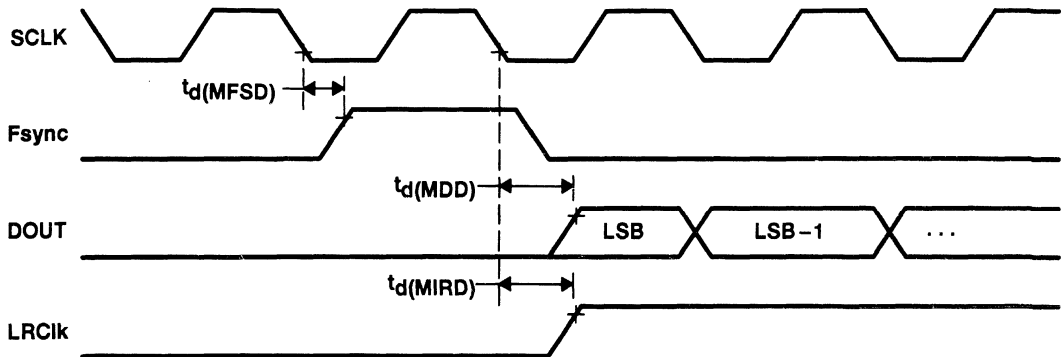


Figure 4-4. SCLK to Fsync, DOUT, and LRCIk – Master Mode 7

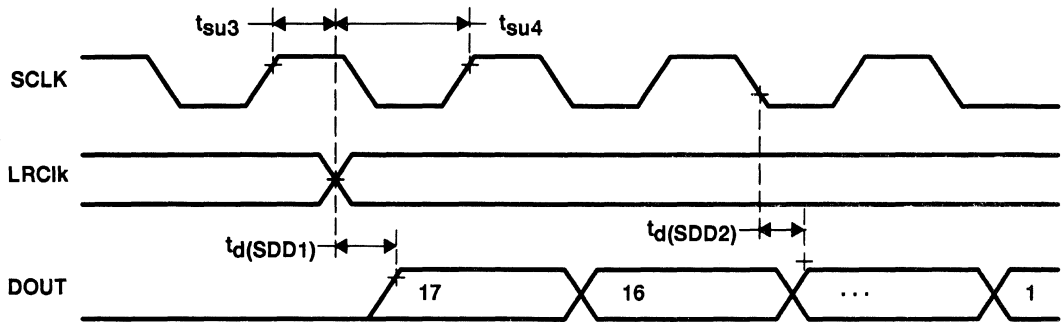


Figure 4-5. SCLK to LRCIk and DOUT – Slave Mode 0, Fsync High

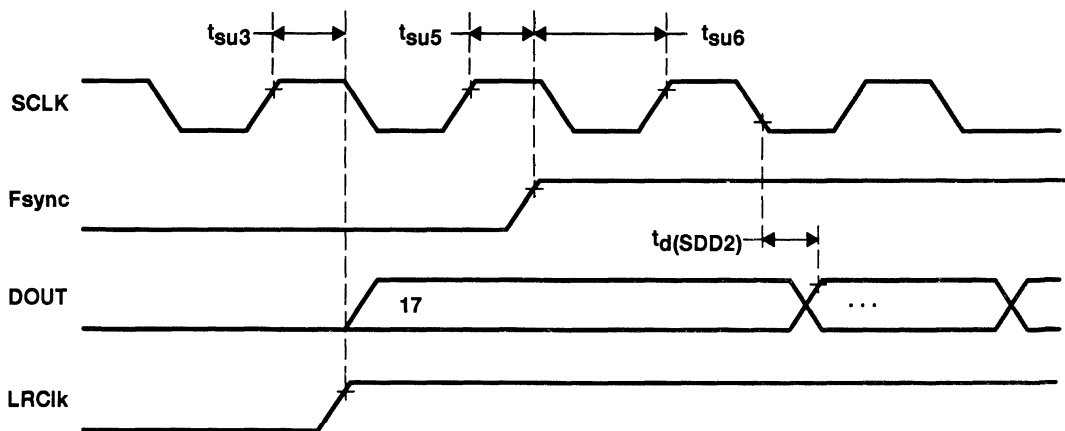


Figure 4-6. SCLK to Fsync, LRCIk, and DOUT – Slave Mode 2, Fsync Controlled

TLC320AD58C ***Data Manual***

Sigma-Delta Stereo Analog-to-Digital Converter



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1 Introduction

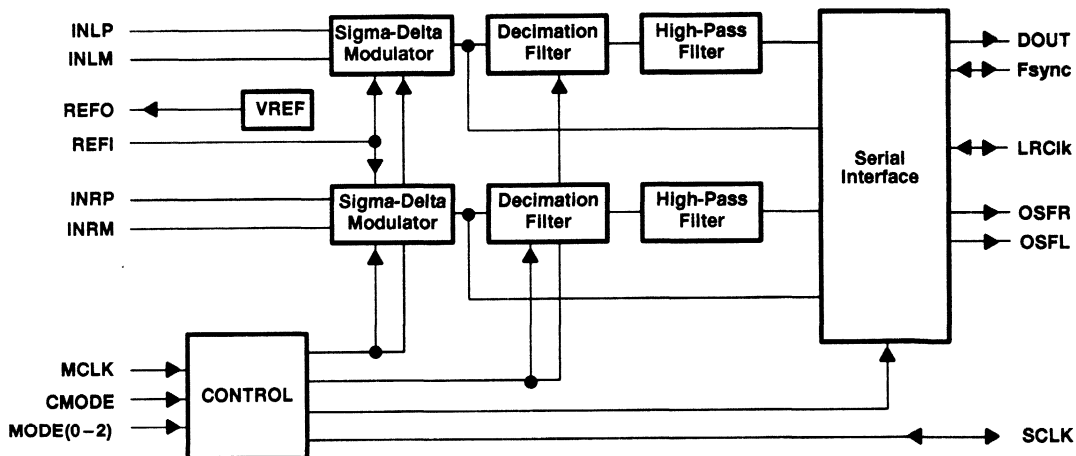
The TLC320AD58C provides high-resolution signal conversion from analog to digital using oversampling sigma-delta technology. This device consists of two synchronous conversion paths. Also included is a decimation filter after the modulator as shown in the functional block diagram. Other functions provide analog filtering and on-chip timing and control.

A functional block diagram of the TLC320AD58C is included in Section 1.2. Each block is described in the detailed description section.

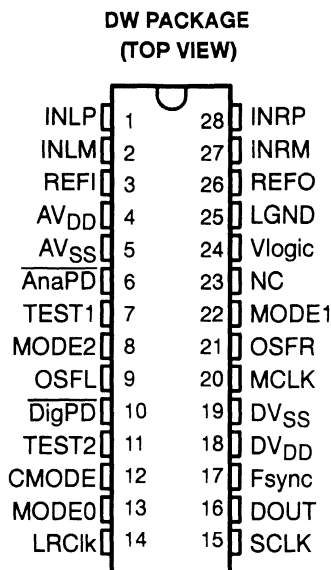
1.1 Features

- Single 5-V Power Supply
- Sample Rates up to 48 kHz
- 18-Bit Resolution
- Signal-to-Noise Ratio (EIAJ) of 97 dB
- Dynamic Range of 95 dB
- Total Signal-to-Noise+Distortion of 95 dB
- Internal Reference Voltage (V_{ref})
- Serial-Port Interface
- Differential Architecture
- Power Dissipation of 200 mW. Power-Down Mode for Low-Power Applications
- One-Micron Advanced LinEPIC1Z™ Process

1.2 Functional Block Diagram



1.3 Terminal Assignments



NC – No internal connection

1.4 Ordering Information

T _A	PACKAGE
	SMALL OUTLINE (DW)
0°C to 70°C	TLC320AD58CDW

1.5 Terminal Functions

TERMINAL NAME	NO.	I/O	DESCRIPTION
AnaPD	6	I	Analog power-down mode. The analog power-down mode disables the analog modulators. The single-bit modulator outputs become invalid, rendering the outputs of the digital filters invalid. When AnaPD is pulled high, normal operation of the device is resumed.
AV _{DD}	4	I	Analog supply voltage
AV _{SS}	5	I	Analog ground
CMODE	12	I	Clock mode. CMODE is used to select between two methods of determining the master clock frequency. When CMODE is high, the master clock input is 384× the conversion frequency. When CMODE is low, the master clock input is 256× the conversion frequency.
DOUT	16	O	Data output. DOUT is used to transmit the sigma-delta audio ADC output data to a DSP serial port or other compatible serial interface and is synchronized to SCLK. This output is low when DigPD is high.
DV _{DD}	18	I	Digital supply voltage
DV _{SS}	19	I	Digital ground
DigPD	10	I	Digital power-down mode. The digital power-down mode shuts down the digital filters and clock generators. All digital outputs are brought to unasserted states. When DigPD is pulled high, normal operation of the device is resumed.
Fsync	17	I/O	Frame sync. Frame sync is used to designate the valid data from the ADC.

1.5 Terminal Functions (Continued)

TERMINAL NAME	NO.	I/O	DESCRIPTION																																				
INLM	2	I	Inverting input to left analog input amplifier																																				
INLP	1	I	Noninverting input to left analog input amplifier																																				
INRM	27	I	Inverting input to right analog input amplifier																																				
INRP	28	I	Noninverting input to right analog input amplifier																																				
LGND	25	I	Logic power supply ground for analog modulator																																				
LRCIk	14	I/O	Left/right clock. LRCIk signifies whether the serial data is associated with the left channel ADC (when LRCIk is high) or the right channel ADC (when LRCIk is low). LRCIk is low when DigPD is low.																																				
MCLK	20	I	Master clock. MCLK is used to derive all the key logic signals of the sigma-delta audio ADC. The nominal input frequency range is 18.432 MHz to 256 kHz.																																				
MODE(0–2)	13, 22, 8	I	<p>Serial modes. MODE(0–2) configure this device for many different modes of operation. The different configurations are:</p> <p>Master versus slave 16 bit versus 18 bit MSB first versus LSB first</p> <p>Slave: Fsync controlled versus Fsync high</p> <p>Each of these modes is described in the serial interface section along with timing diagrams.</p> <table border="1"> <thead> <tr> <th>MODE</th> <th>MASTER/ SLAVE</th> <th>BITS</th> <th>MSB/LSB FIRST</th> </tr> </thead> <tbody> <tr> <td>0 0 0</td> <td>slave</td> <td>up to 18</td> <td>MSB</td> </tr> <tr> <td>0 0 1</td> <td>slave</td> <td>18</td> <td>LSB</td> </tr> <tr> <td>0 1 0</td> <td>slave</td> <td>up to 18</td> <td>MSB</td> </tr> <tr> <td>0 1 1</td> <td>master</td> <td>16</td> <td>MSB</td> </tr> <tr> <td>1 0 0</td> <td>master</td> <td>18</td> <td>MSB</td> </tr> <tr> <td>1 0 1</td> <td>master</td> <td>18</td> <td>LSB</td> </tr> <tr> <td>1 1 0</td> <td>master</td> <td>16</td> <td>MSB</td> </tr> <tr> <td>1 1 1</td> <td>master</td> <td>16</td> <td>LSB</td> </tr> </tbody> </table>	MODE	MASTER/ SLAVE	BITS	MSB/LSB FIRST	0 0 0	slave	up to 18	MSB	0 0 1	slave	18	LSB	0 1 0	slave	up to 18	MSB	0 1 1	master	16	MSB	1 0 0	master	18	MSB	1 0 1	master	18	LSB	1 1 0	master	16	MSB	1 1 1	master	16	LSB
MODE	MASTER/ SLAVE	BITS	MSB/LSB FIRST																																				
0 0 0	slave	up to 18	MSB																																				
0 0 1	slave	18	LSB																																				
0 1 0	slave	up to 18	MSB																																				
0 1 1	master	16	MSB																																				
1 0 0	master	18	MSB																																				
1 0 1	master	18	LSB																																				
1 1 0	master	16	MSB																																				
1 1 1	master	16	LSB																																				
OSFL, OSFR	9, 21	O	Over scale flag left/right. If the left/right channel digital output exceeds full scale output range for two consecutive conversions, this flag is set high for 4096 LRCIk periods. OSFL and OSFR are low when DigPD is low.																																				
SCLK	15	I/O	Shift clock. If SCLK is configured as an input, SCLK is used to clock serial data out of the sigma-delta audio ADC. If SCLK is configured as an output, SCLK stops clocking when DigPD is low.																																				
TEST1	7	I	Test mode 1. TEST1 should be low for normal operation.																																				
TEST2	11	I	Test mode 2. TEST2 should be low for normal operation.																																				
REFI	3	I	Input voltage for modulator reference (normally connected to REFO, terminal 26).																																				
REFO	26	I	Internal voltage reference																																				
Vlogic	24	I	Logic power supply voltage (5 V) for analog modulator																																				

2 Detailed Description

The sigma-delta converter allows for simple antialias external filtering. Typically, a first order RC filter is sufficient.

2.1 Power-Down and Reset Functions

2.1.1 Power Down

The power-down state is comprised of a separate digital and analog power down. The power consumption of each is detailed in the electrical characteristics section.

The digital power-down mode shuts down the digital filters and clock generators. All digital outputs are set to an unasserted level. When the digital power-down terminal is pulled high, normal operation of the device is initiated. In slave mode, the conversion process must synchronize to an input on the LRCIk terminal as well as the SCLK terminal. Therefore, the conversion process is not initiated until the first rising edges of both SCLK and LRCIk are detected after $\overline{\text{DigPD}}$ is pulled high. This synchronizes the conversion cycle; all conversions are performed at a fixed LRCIk rate [MCLK/256 (CMODE low) or MCLK/384 (CMODE high)] after the initial synchronization. After the digital power-down terminal is brought high, the output of the digital filters remains invalid for 50 LRCIk cycles [see Figures 2–1(a) and 2–1(b)].

In master mode, LRCIk is an output; therefore, the conversion process initiates based on internal timing. The first valid data out occurs as shown in Figure 2–1(c).

The analog power-down mode disables the analog modulators. The single-bit modulator outputs become invalid which renders the outputs of the digital filters invalid. When the analog power-down terminal is brought high, the modulators are brought back online; however, the outputs of the digital filters require 50 LRCIk cycles for valid results.

2.1.2 Reset Function

The conversion process is not initiated until the first rising edges of both SCLK and LRCIk are detected after $\overline{\text{DigPD}}$ is pulled high. This synchronizes the conversion cycle; all conversions are performed at a fixed LRCIk rate [MCLK/256 (CMODE low) or MCLK/384 (CMODE high)] after the initial synchronization.

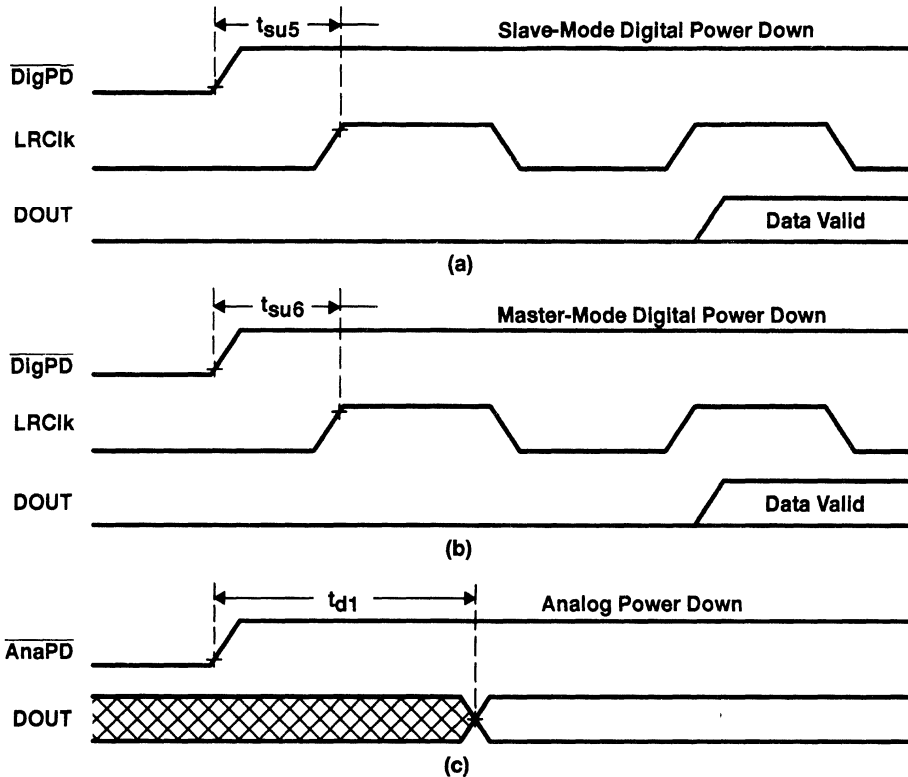


Figure 2–1. Power-Down Timing Relationships

2.2 Differential Input

The input is differential in order to provide common-mode noise rejection and increase the input dynamic range. Figure 2–2 shows the analog input signals used in a differential configuration to achieve a $6.4 V_{I(PP)}$ differential swing with a $3.2 V_{I(PP)}$ swing per input line. Both a differential and a single-ended configuration are shown in the application information section.

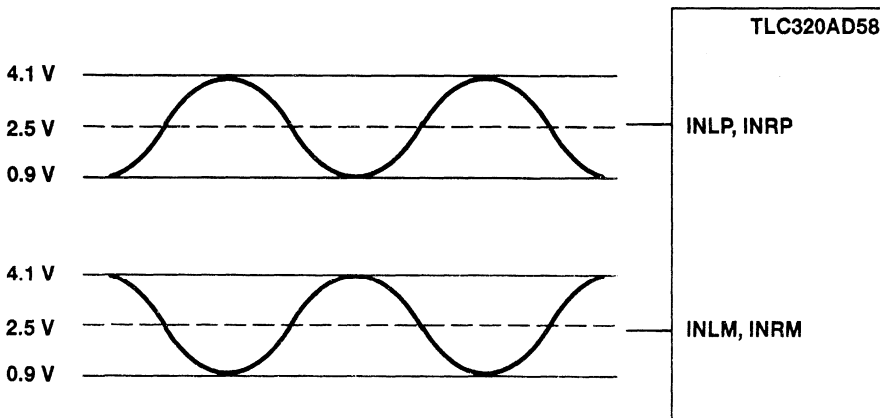


Figure 2–2. Differential Analog Input Configuration

2.3 Sigma-Delta Modulator

The modulator is a fourth-order sigma-delta modulator with 64 times oversampling. The ADC provides high-resolution, low-noise performance from a one-bit converter using oversampling techniques.

2.4 Decimation Filter

The decimation filter used after the sigma-delta modulator reduces the digital data rate to the sampling rate of LRClk. This is accomplished by decimating with a ratio of 1:64. The output of this filter is a 2s complement data word of up to 18 bits serially clocked out.

If the input value exceeds the full range of the converter, the output of the decimator is held at the appropriate extreme until the input returns to the dynamic range of this device.

2.5 High-Pass Filter

The high-pass filter removes dc from the input.

2.6 Master-Clock Circuit

The master-clock circuit is used to generate and distribute necessary clocks throughout the device. MCLK is the external master clock input. CMODE is used to select the relationship of MCLK to the sample rate of LRClk. When CMODE is low, the sample rate of the data paths is set as $LRClk = MCLK/256$. When CMODE is high, the sample rate is set as $LRClk = MCLK/384$. With a fixed oversampling ratio of 64x, the effect of changing MCLK is shown in Table 2–1.

When the TLC320AD58C is in master mode, SCLK is derived from MCLK in order to provide clocking of the serial communications between the sigma-delta audio ADC and a digital signal processor (DSP) or control logic. This is equivalent to a clock running at $64 \times LRClk$.

When the TLC320AD58C is in slave mode, SCLK is externally derived.

**Table 2–1. Master-Clock to Sample-Rate Comparison
(Modes 1, 3, 4, 5)**

MCLK (MHz)	CMODE	SCLK (MHz)	LRClk (kHz)
12.2880	Low	3.0720	48
18.4320	High		
11.2896	Low	2.8224	44.1
16.9344	High		
8.1920	Low	2.0480	32
12.2880	High		
0.2560	Low	0.0640	1
0.3840	High		

2.7 Test

TEST1 and TEST2 are reserved for factory test and should be tied to digital ground (DV_{SS}).

2.8 Serial Interface

Although the serial data is shifted out in two separate time packets that represent the left and right channels, the inputs are sampled and converted simultaneously.

The serial interface protocol has master and slave modes each with different read out modes. The master mode is used to source the control signals for conversion synchronization, while the slave mode allows an external controller to provide conversion synchronization signals.

The five master modes are shown in Figures 2–3(a) through 2–3(e), and the three slave modes are shown in Figures 2–4(a) through 2–4(c). For a 16-bit word, D15 is the most significant bit and D0 is the least significant bit. Unless otherwise specified, all values are in 2s complement format.

In master mode, SCLK is generated internally and is sourced as an output. The relationship of SCLK to LRClk is 64× (modes 1, 3, 4, 5) or 32× (modes 6, 7). In slave mode, SCLK is an input. SCLK timing must meet the timing specifications shown in the recommended operating conditions section.

2.8.1 Master Mode

As the master, the TLC320AD58C generates LRClk, Fsync, and SCLK from MCLK. These signals are provided for synchronizing the serial port of a digital signal processor (DSP) or other control devices.

Fsync is used to designate the valid data from the ADC, and this is accomplished in the master modes by one of two methods. The first is a single pulse on Fsync prior to valid data. This indicates the starting point for the data. The second method of frame synchronization is to hold Fsync high during the entire valid data cycle, which provides boundaries for the data.

LRClk is generated internally from MCLK. The frequency of this signal is fixed at the sampling frequency f_s [$MCLK/256$ (CMODE low) or $MCLK/384$ (CMODE high)]. During the high period of this signal, the left channel data is serially shifted to the output; during the low period, the right channel data is shifted to the output. The conversion cycle is synchronized with the rising edge of LRClk.

Five modes are available when the device is configured as a master. Two modes are for 18-bit communications. These modes differ from each other in that the MSB is transferred first in one mode while the LSB is transferred first in the second mode [see Figures 2–3(b) and 2–3(c)]. When the LSB is transferred first, the data is right justified to the LRClk [see Figures 2–3(a) through 2–3(e)]. The three other master modes are 16-bit modes. Once again, two of the modes differ as MSB first versus LSB first. These two modes set $SCLK = LRClk \times 32$. This is half the frequency used in the other transfer modes [see Figures 2–3(d) and 2–3(e)]. The third 16-bit mode provides the data MSB first with one clock delay after LRClk [see Figure 2–3(a)].

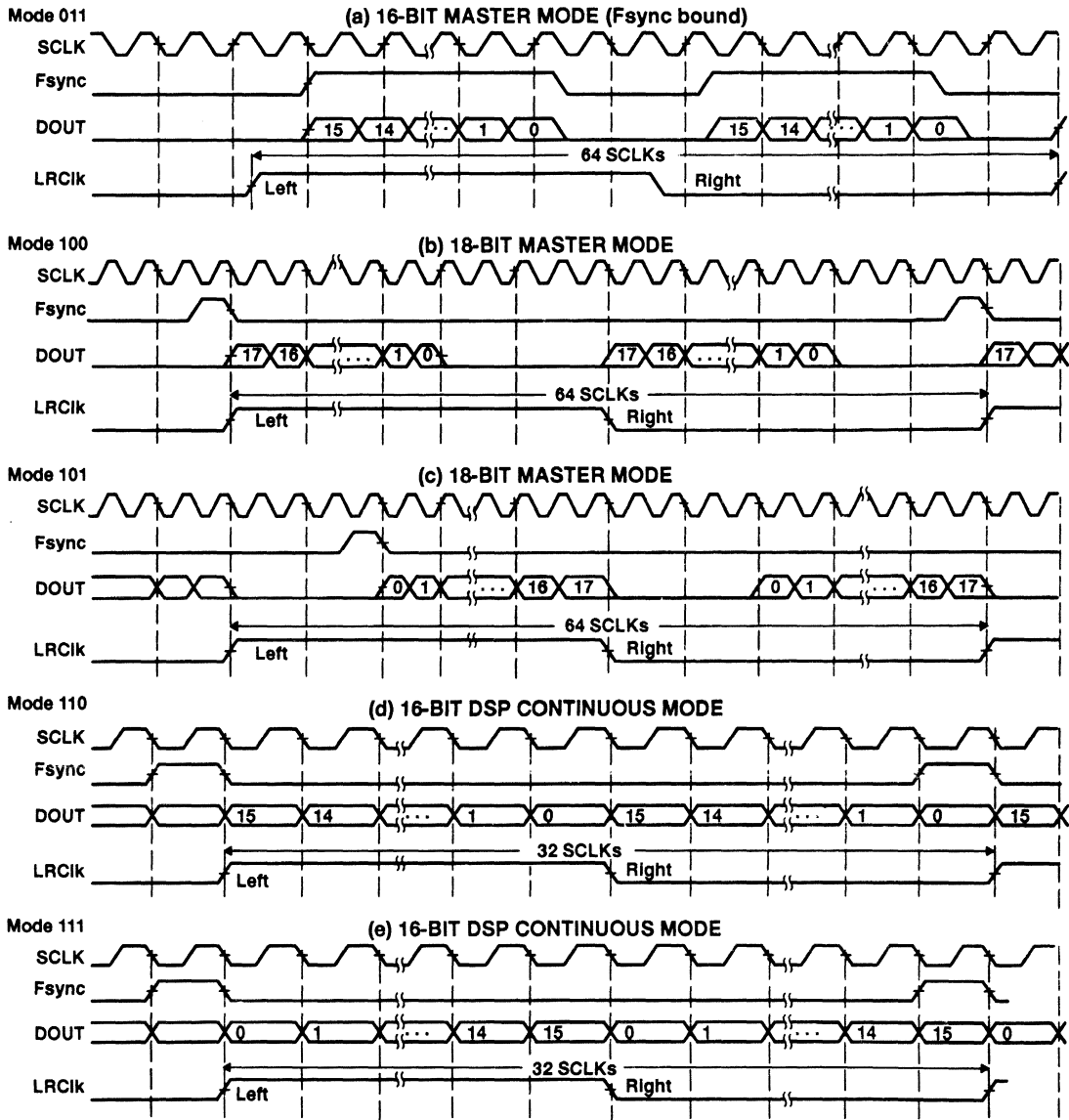


Figure 2-3. Serial Master Transfer Modes

2.8.2 Slave Mode

As a slave, the TLC320AD58C receives LRCik, Fsync, and SCLK as inputs. The conversion cycle is synchronized to the rising edge of LRCik, and the data is synchronized to the falling edge of SCLK. SCLK must meet the setup requirements specified in the recommended operating conditions section. Synchronization of the slave modes is accomplished with the digital power-down control.

In slave mode, Fsync is an input. Three modes are provided as shown in Figures 2-4(a) through 2-4(c). SCLK and LRCik are externally generated and sourced. The first rising edges of SCLK and LRCik after a power-down cycle initiate the conversion cycle. Refer to the master-mode section for signal functions.

Several modes are available when the TLC320AD58C is configured as a slave. Using the Mode0, Mode1, and Mode2 terminals, the TLC320AD58C can be set to shift out the MSB first or the LSB first [see Figures 2-4(a) and 2-4(b)]. The number of bits shifted out, however, can be controlled by the number of valid SCLK cycles provided within the left or right channel period. If only enough clocks are provided to shift out 16 data bits before LRCIk changes state, then this is equivalent to a 16-bit mode. Modes 1 and 2 both require 64 SCLK periods per LRCIk period.

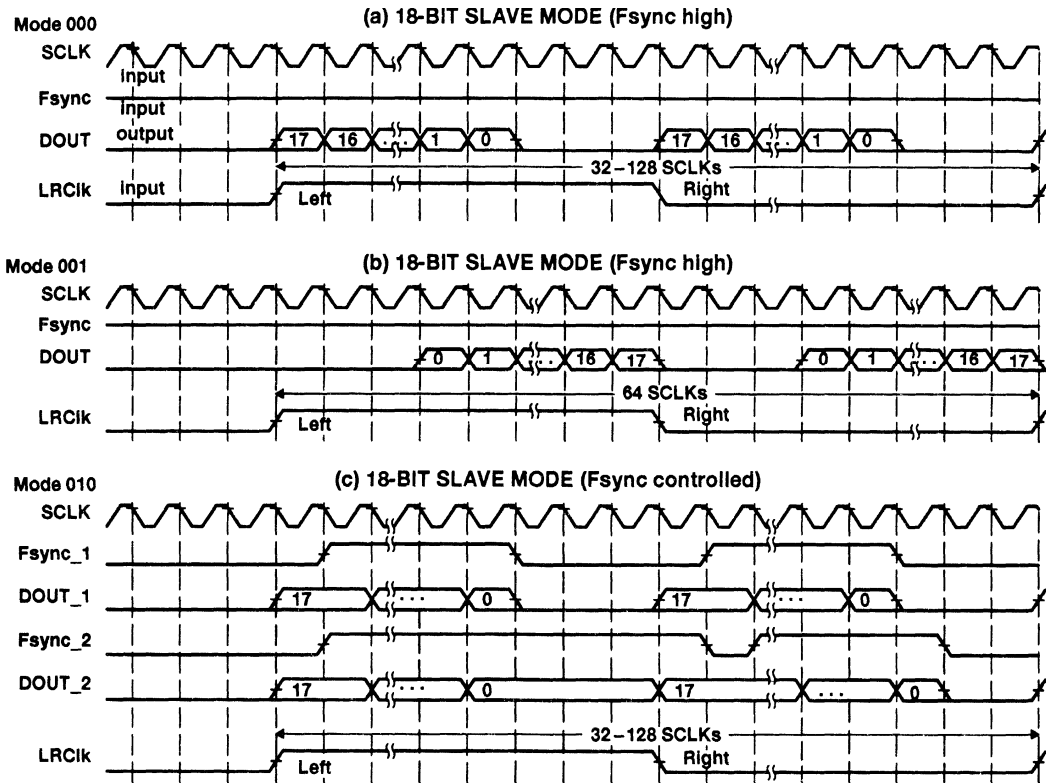


Figure 2-4. Serial Slave Transfer Modes

3 Specifications

3.1 Absolute Maximum Ratings Over Operating Free-Air Temperature Range (unless otherwise noted)†

Supply voltage range, AV_{DD} (see Note 1)	-0.3 V to 6.5 V
Supply voltage range, DV_{DD} (see Note 2)	-0.3 V to 6.5 V
Analog input voltage range, INLP, INLM, INRP, INRM	-0.3 V to 6.5 V
Operating free-air temperature range, T_A	-0°C to 70°C
Storage temperature range, T_{stg}	-65°C to 150°C
Case temperature for 10 seconds	260°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds	260°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. Voltage values for maximum ratings are with respect to AV_{SS} .
2. Voltage values for maximum ratings are with respect to DV_{SS} .

3.2 Recommended Operating Conditions

	MIN	NOM	MAX	UNIT
Analog supply voltage, AV_{DD} (see Note 3)	4.75	5	5.25	V
Digital supply voltage, DV_{DD}	4.75	5	5.25	V
Analog logic supply voltage, V_{logic}	4.75	5	5.25	V
Reference voltage, V_{ref}		3.2		V
Setup time, $SCLK\uparrow$ to $LRCIk$, slave mode, t_{su1}	30			ns
Setup time, $LRCIk$ to $SCLK\uparrow$, slave mode, t_{su2}	30			ns
Setup time, $SCLK\uparrow$ to $Fsync$, slave mode, t_{su3}	30			ns
Setup time, $Fsync$ to $SCLK\uparrow$, slave mode, t_{su4}	30			ns
Setup time, \overline{DigPD} to $LRCIk\uparrow$, slave mode, t_{su5}		30		ns
Setup time, \overline{DigPD} to $LRCIk\uparrow$, master mode, t_{su6}		30		ns
Load resistance at $DOUT$, R_L		10		k Ω
Input dc offset range	-50	0	50	mV
Operating free-air temperature, T_A	0		70	°C

NOTE 3: Voltages at analog inputs and outputs and AV_{DD} are with respect to the AV_{SS} terminal.

3.3 Electrical Characteristics

3.3.1 Digital Interface, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V_{IH}	High-level input voltage		2	4.6		V
V_{IL}	Low-level input voltage			0.2	0.8	V
V_{OH}	High-level output voltage at DOUT	$I_{OH} = 2\text{ mA}$	2.4	4.6		V
V_{OL}	Low-level output voltage at DOUT	$I_{OL} = 2\text{ mA}$		0.2	0.4	V
I_{IH}	High-level input current, any digital input			1		μA
I_{IL}	Low-level input current, any digital input			1		μA
C_i	Input capacitance			5		pF
C_o	Output capacitance			5		pF

3.3.2 Analog Interface

3.3.2.1 ADC Modulator, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$, $f_s = 48\text{ kHz}$, Bandwidth = 24 kHz, $\text{CMODE} = 0$, $\text{MODE}(0-2) = 000$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Resolution			18		Bits
DYNAMIC PERFORMANCE	ANSI A-weighting filter				
Signal to noise (EIAJ)	$\text{INLP} = \text{INRP} = 2.5\text{ V dc}$ $\text{INLM} = \text{INRM} = 2.5\text{ V dc}$	96	100		dB
Dynamic range	-1 dB down from 6-V differential input	90	95		dB
Signal to noise + distortion (THD + N)		88	93		dB
Total harmonic distortion (THD)			0.0015%		
Interchannel isolation			120		dB
DC ACCURACY					
Absolute gain error			± 0.6		dB
Interchannel gain mismatch			± 0.2		dB
Offset error (18-bit resolution)			120 ± 5		mV
Offset drift			± 0.17		LSB/ $^\circ\text{C}$

3.3.2.2 Inputs/Supplies, $T_A = 25^\circ\text{C}$, $AV_{DD} = DV_{DD} = 5\text{ V}$, $f_s = 48\text{ kHz}$, Bandwidth = 24 kHz

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
ANALOG INPUT					
Input voltage range	(differential)		6.2		V
	(0 to peak)		3.1		
Input impedance			200		$\text{k}\Omega$
POWER SUPPLIES					
Power-supply current	I_{DD} (analog), normal mode		24	32	mA
	I_{DD} (digital), normal mode		26	32	mA
	I_{DD} (analog), power down		250		μA
	I_{DD} (digital), power down		150		μA
Power dissipation			250		mW

3.3 Electrical Characteristics (Continued)

3.3.3 Channel Characteristics, $T_A = 25^\circ\text{C}$, $V_{DD} = DV_{DD} = 5\text{ V}$, $f_s = 48\text{ kHz}$

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
Passband (-3 dB)		0.001		24	kHz
Passband ripple	30 Hz – 21.8 kHz		± 0.01		dB
Stopband attenuation	26.2 kHz – 3046 kHz	80			dB
Group delay			$25/f_s$		s

3.4 Switching Characteristics

PARAMETER	MIN	TYP	MAX	UNIT
t_{d1} Delay time, $\overline{\text{AnaPD}}$ to DOUT valid		30		ns
$t_d(\text{MFSD})$ Delay time, SCLK \downarrow to Fsync, master mode	-20		20	ns
$t_d(\text{MDD})$ Delay time, SCLK \downarrow to DOUT, master mode	0		50	ns
$t_d(\text{MIRD})$ Delay time, SCLK \downarrow to LRCIk, master mode	-20		20	ns
$t_d(\text{SDD1})$ Delay time, LRCIk to DOUT, slave mode			50	ns
$t_d(\text{SDD2})$ Delay time, SCLK \downarrow to DOUT, slave mode			50	ns

4 Parameter Measurement Information

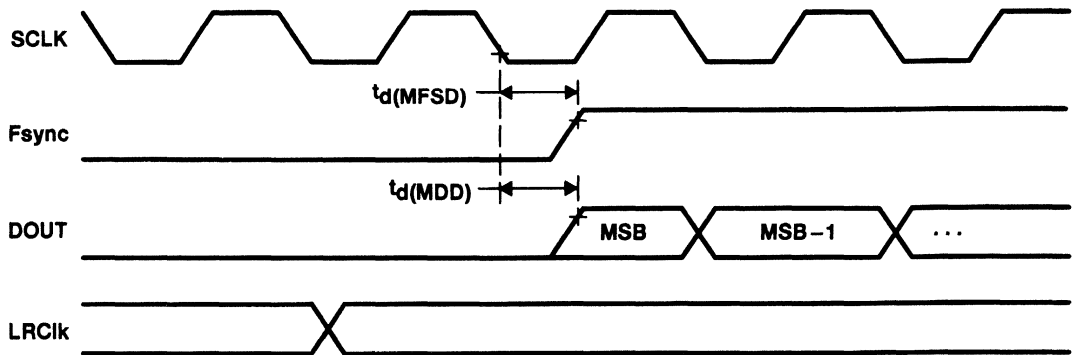


Figure 4-1. SCLK to Fsync and DOUT – Master Mode 3

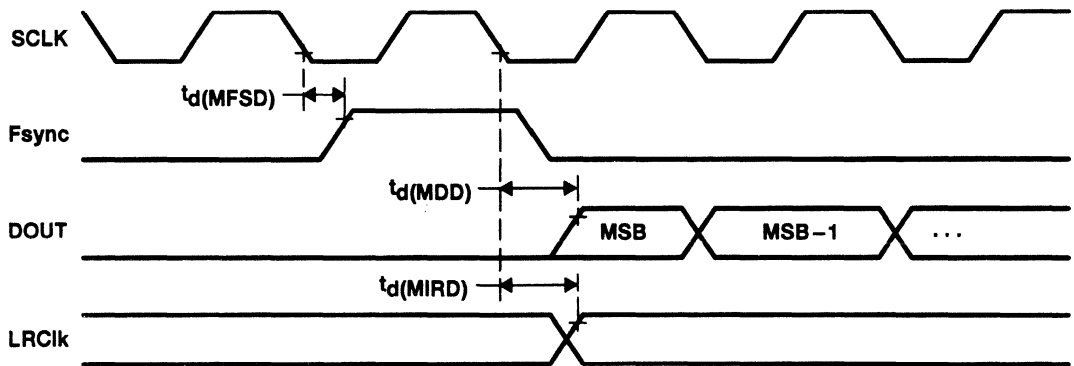


Figure 4-2. SCLK to Fsync, DOUT, and LRCIk – Master Modes 4 and 6

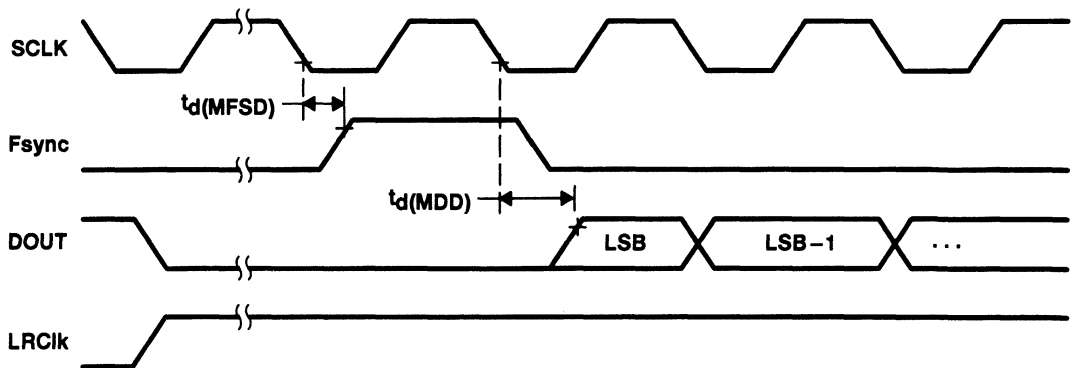


Figure 4-3. SCLK to Fsync, DOUT, and LRCIk – Master Mode 5

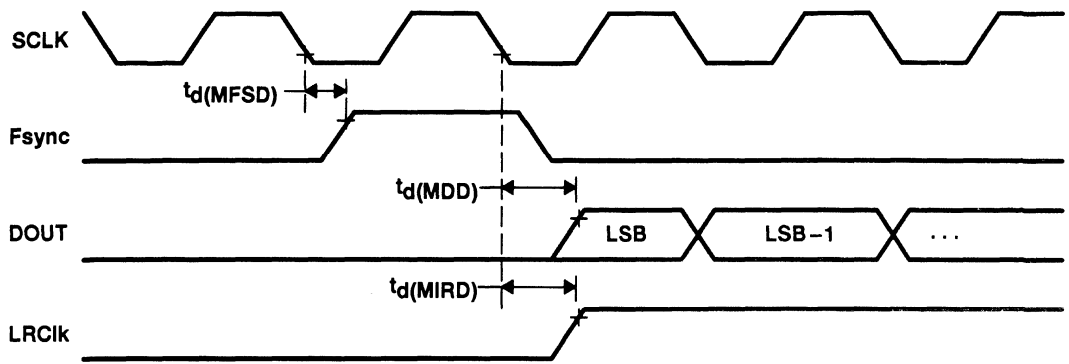


Figure 4-4. SCLK to Fsync, DOUT, and LRCIk – Master Mode 7

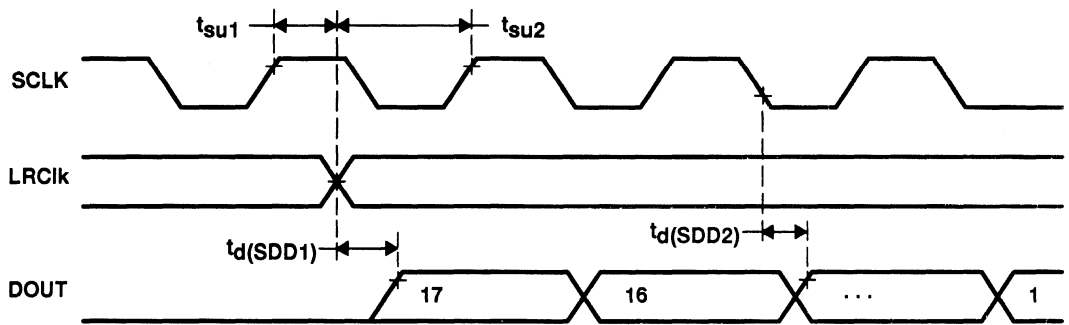


Figure 4-5. SCLK to LRCIk and DOUT – Slave Mode 0, Fsync High

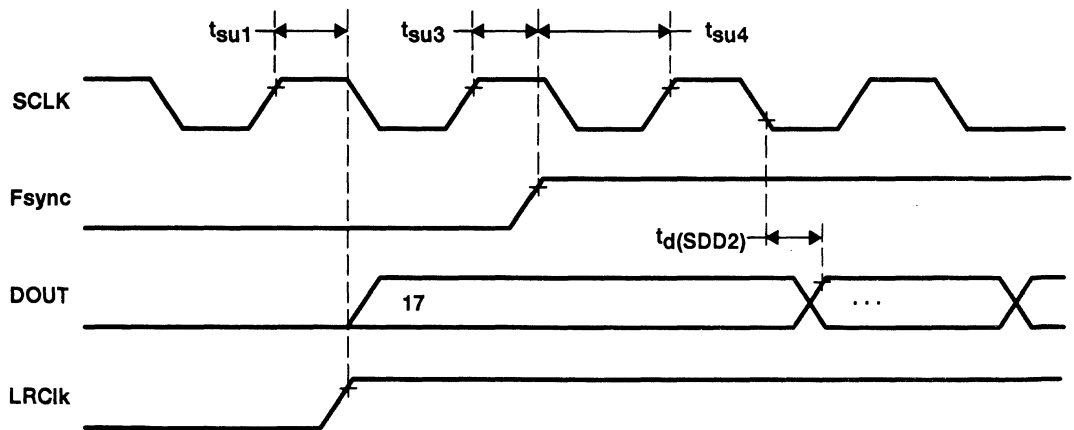


Figure 4-6. SCLK to Fsync, LRCIk, and DOUT – Slave Mode 2, Fsync Controlled

5 Application Information

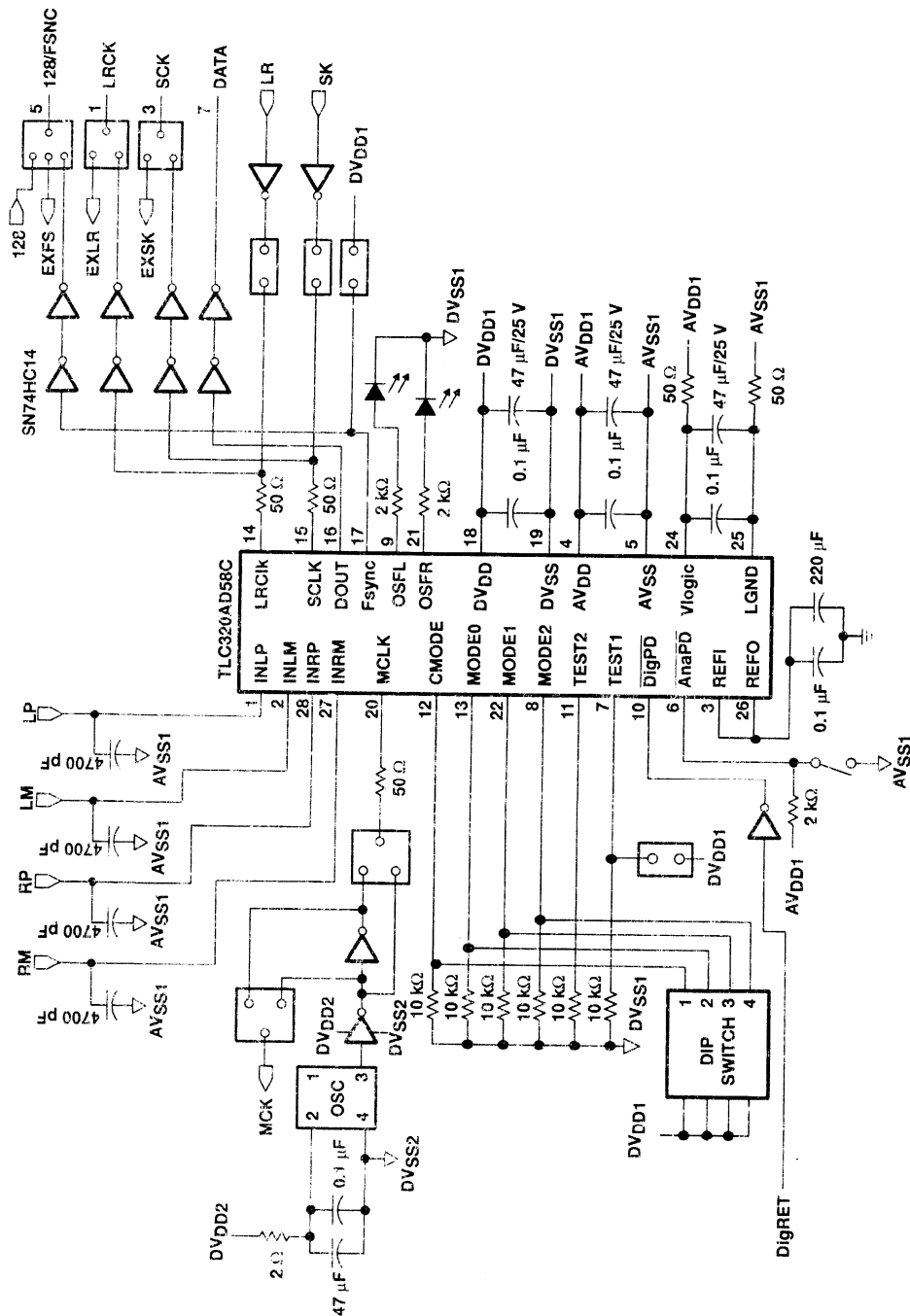


Figure 5-1. TLC320AD58C Configuration Schematic

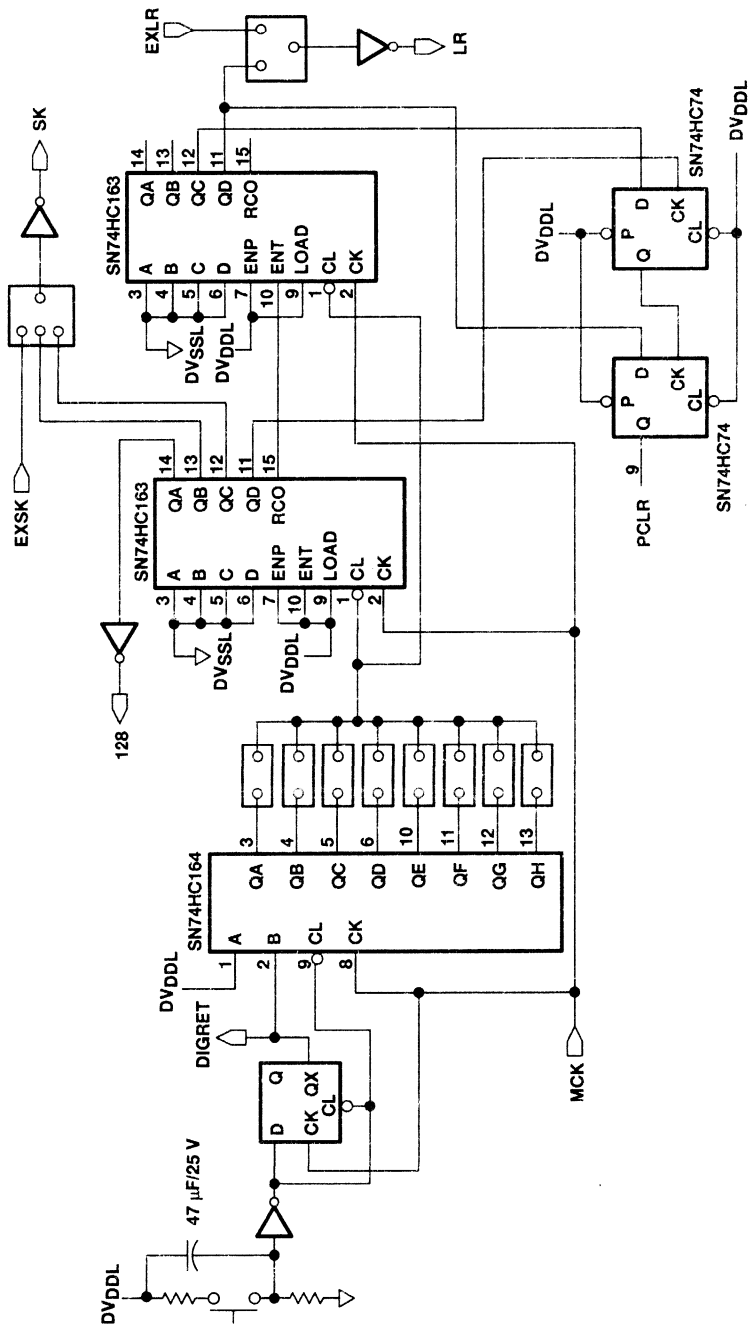


Figure 5-2. TLC320AD58C External Digital Timing and Control-Signal Generation Schematic

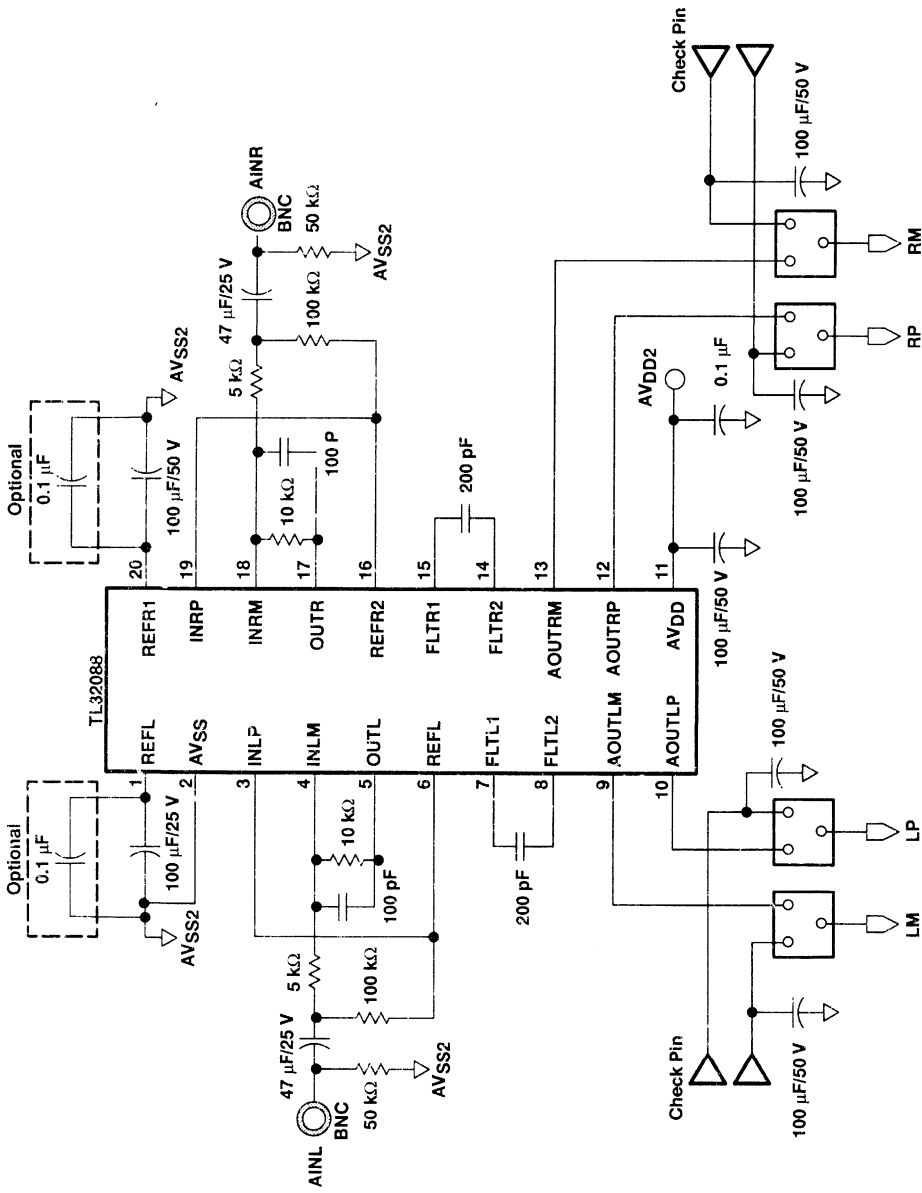


Figure 5-3. TL-C320AD58C External Analog Input Buffer Schematic

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Application Reports

TL7726
Hex Clamping Circuit

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Introduction

This application report describes both the parasitic effects present in integrated circuits (ICs) and the problems that can result when protecting precision analog components with conventional methods. Specifically illustrated are how these problems can be overcome by using the TL7726 hex clamping circuit.

All semiconductor ICs, regardless of function and manufacturer, are vulnerable to voltages and currents exceeding the absolute maximum ratings. Although semiconductor manufacturers often build in protection features such as electrostatic-discharge (ESD) protection, voltage clamping, and current limitation, the devices may fail if operated outside the manufacturer's absolute maximum ratings.

Main failure mechanisms result from overvoltage stress of the semiconductor material. CMOS devices are particularly vulnerable in this regard, even at low-voltage levels, due to inherent parasitic structures. The best understood parasitic effect is latch-up, which is caused by parasitic thyristor action caused by overvoltage stress. If sufficient current is injected into either the input or output pins of the device, the thyristor triggers and a short circuit results between the supply rails (latch-up). This usually results in catastrophic device failure.

Through careful semiconductor design and by using the device within the manufacturers' absolute maximum voltage ratings, the effects of overvoltage stress can be greatly reduced. For precision analog circuits, this externally applied voltage level should be tightly controlled; the voltage should be no more than 0.3 V above the positive supply or 0.3 V below ground. Since it is difficult to predict if an applied voltage falls within these limits, external clamping circuits in the form of silicon diodes are often employed.

Zener diodes seem to be an obvious choice for this function. Unfortunately, due to poor voltage tolerance and asymmetrical clamping, the protected circuitry may not only be inadequately clamped but may suffer from reduced performance. For example, the dynamic range of an analog-to-digital converter may be reduced.

The preferred use of Schottky diodes proves similarly inadequate. The forward voltage of a Schottky diode is 400 mV. While this can protect the device for the majority of fault conditions, it still allows voltage levels in excess of the manufacturers' absolute maximum levels to be developed across the device. In effect, the device is being operated outside the recommended conditions and its continued function may be impaired.

Parasitic Transistors in Complementary MOS Circuits

The normal operating effects of the parasitic transistors inherent when making complementary MOS (CMOS) components is not particularly critical; however, the resultant structures shown in Figure 1 allow a clear explanation of parasitic effects when operation is not restricted to normal ranges.

The manufacturing process of high-speed digital CMOS circuits begins with an N-doped substrate (see Figure 1) into which a P-doped well is diffused followed by N-doped regions for the drains and sources of the N-channel transistors; the well itself is connected via a P-doped contact to the substrate (GND). P-doped zones in the N-doped substrate provide the drains and sources of the P-channel transistors.

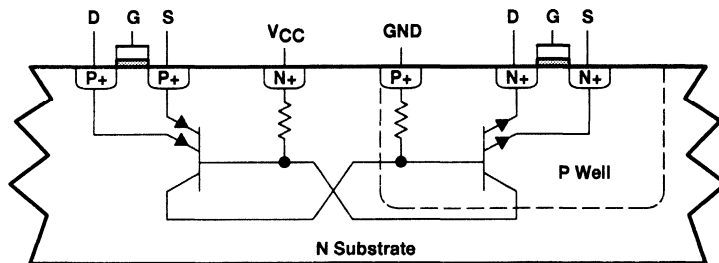


Figure 1. Parasitic Bipolar Transistors in CMOS Circuits

Latch-Up

The substrate itself is connected to the positive supply voltage (V_{CC}) via an N-doped contact. This produces both parasitic npn and pnp transistors; together these make up a pnpn structure of a thyristor (see Figure 2). The anode of this parasitic thyristor is connected to the positive supply and the cathode to GND; all other connections to this element (inputs and outputs) are gates of the thyristor. If a large enough current is injected into the input or output of this element, the thyristor is triggered. This effect is known as latch-up, and the resulting short circuit between the supply rails usually causes destruction of the component.

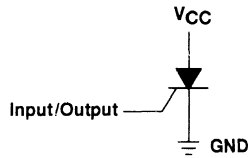


Figure 2. Structure of Parasitic Thyristor

Guard Rings

Latch-up effects have been reduced by incorporating additional guard rings in the structure. Guard rings are circular N- or P-doped zones surrounding the endangered elements, the N zones being connected to the positive supply rail and the P zones to the most negative supply rail (usually the substrate supply rails). These guard rings (see Figure 3) provide additional collectors for the parasitic transistors, which collect most of the current circulating in the substrate and divert it to the supply voltage rails; to a large extent, these eliminate the danger of latch-up. With modern logic circuits, such as high-speed CMOS, guard rings prevent latch-up from occurring until at least 300 mA is injected into an input or output at an operating temperature of 125°C. Since the gain of the parasitic transistors decreases at lower temperatures, the sensitivity of the thyristors at lower temperatures is reduced. At normal temperatures with careful device design, currents of over 1 A are necessary to provoke latch-up.

Linear CMOS (analog process) ICs are tested for susceptibility to latch-up by injecting a current pulse with an amplitude of 100 mA at an ambient temperature of 25°C into the inputs and outputs. This current is chosen to simulate a practical overload condition, while eliminating any risk of damage. The protective elements of ICs are in fact designed to withstand, without risk of damage, a continuous current of 5 mA in the clamping diodes.

The danger of component destruction as a result of latch-up due to parasitic transistors can therefore be reduced with careful chip design but does not entirely eliminate them; this is particularly evident with high-impedance (high-sensitivity) circuits.

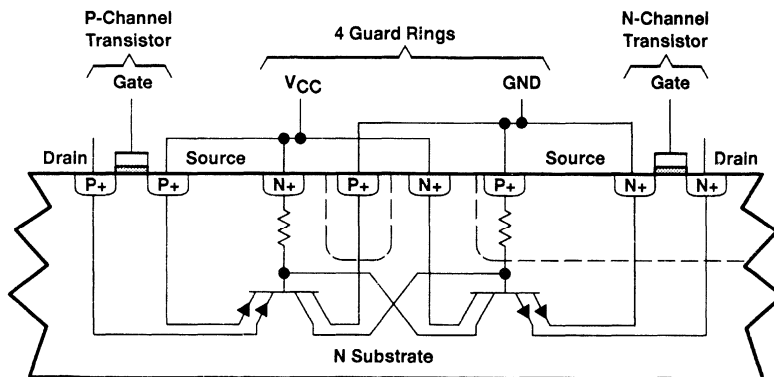


Figure 3. Guard Rings in CMOS Circuits

CMOS Internal-Input-Protection Circuitry

Use CMOS-input diode-protection circuitry, as shown in Figure 4, and assume the input is derived from the voltage source $V_1 = 24\text{ V}$. The supply voltage (V_{CC}) is 5 V . A series resistor ($R_1 = 100\text{ k}\Omega$) ensures that the current in the internal clamping diode (D1) is limited to an acceptable value. A potential problem can occur if a neighboring input is connected similarly and is then controlled by the voltage source $V_2 = 0\text{ V}$. In this case, a pnp transistor is created between the two clamping diodes D1 and D2. As a result, part of the current flowing through D1 (emitter) is diverted to D2 (collector); the N-doped substrate, which is connected to the supply voltage, then functions as the base of a parasitic transistor. Even when the gain of this transistor is comparatively low ($0.01 - 0.1$), the current through the R_2 resistor creates a voltage drop that distorts the signal at the input and causes malfunction.

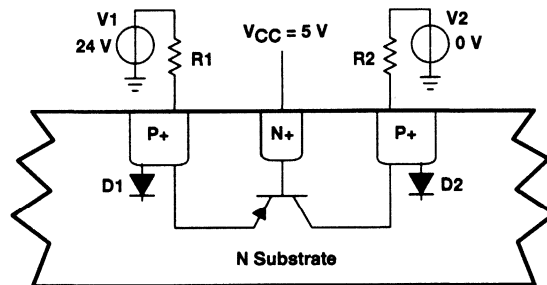


Figure 4. Parasitic Transistors in Input-Protection Circuits

This effect can be reduced through the use of additional guard rings (see Figure 3) but not entirely eliminated. Absolute maximum input voltages are given in data sheets, and if these limits are observed, parasitic effects will be insignificant. With digital CMOS circuits, it is permissible for the input voltage to be up to 0.5 V more positive than V_{CC} or 0.5 V more negative than the substrate without danger of malfunction. With analog circuits that operate at currents several orders of magnitude lower, voltage must be more tightly controlled; the input voltage should not be allowed to be more than 0.3 V above or below the supply voltage.

Silicon integrated protection or clamping diodes have a typical forward voltage (V_f) of 0.7 V at room temperature. The input voltage delta is 0.3 V , since the negative temperature coefficient of the forward voltage ($\approx -2\text{ mV}/^\circ\text{C}$) must be taken into account. As mentioned before, sensitive circuits can malfunction with currents of only a few microamps, at which the forward voltage of a silicon diode at room temperature may be significantly below 0.7 V .

If under any conditions input voltages could exceed these maximum values, then additional precautions are necessary; these usually take the form of external clamping diodes on the input (see Figure 5).

External Clamping Diodes

Silicon diodes are of only limited use for protection since their forward voltage is close to that of the clamping diodes that are already integrated into an IC; therefore, only a part of the excess current is diverted into the external diodes. This approach is suitable when the circuit needs to be protected only from destruction. Because of their smaller geometry, the integrated clamping diodes have a higher forward resistance so a majority of the current is diverted to the external diodes. As protection against malfunction, conventional silicon diodes are not totally effective.

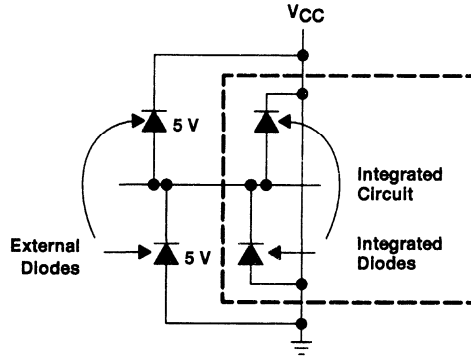


Figure 5. Protection Circuit With External Clamping Diodes

Better results can be expected with the use of germanium or Schottky diodes. These have significantly lower forward voltages (germanium: $V_f = 0.3 \text{ V}$, Schottky: $V_f = 0.4 \text{ V}$). Germanium diodes are seldom used at the present time, have high-leakage characteristics, and can be hard to obtain. If either diode has excessively high forward resistance, they are ineffective anyway.

TL7726 Hex Clamping Circuit

In order to prevent the activation of parasitic transistors, clamping diodes with exceptionally low forward voltages are necessary, and these can only be realized with an active circuit, as shown in Figure 6.

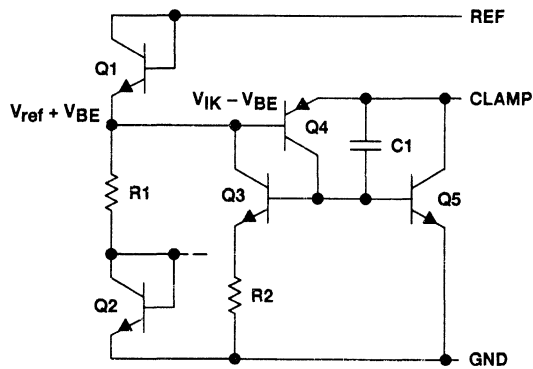


Figure 6. Simplified Circuit of the TL7726

Due to the effects described previously, neither diodes or conventional components are a panacea for protection, particularly for the demanding requirements of analog applications. For this reason, Texas Instruments has developed a dedicated IC that fully meets such requirements, the TL7726 hex clamping circuit. Figure 7 compares the current and voltage characteristics for a range of silicon diodes and a typical TL7726.

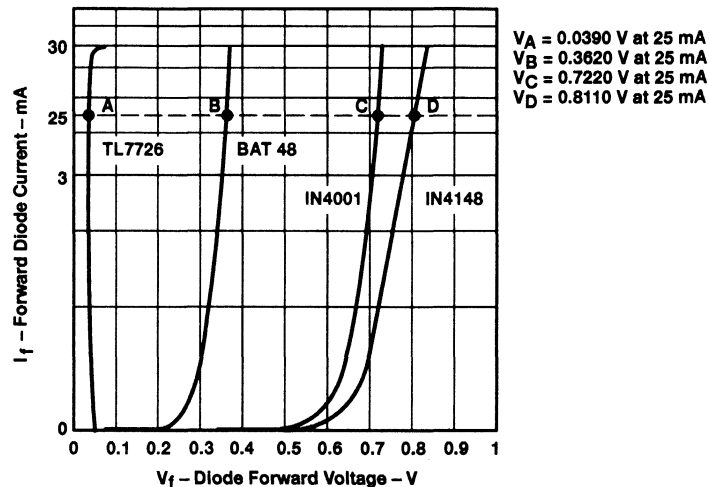


Figure 7. Current and Voltage Characteristics for Various Devices

Device Description

The TL7726 is comprised of six identical active voltage clamping circuits that have been specifically designed to protect vulnerable analog inputs from overvoltage stress. Under fault conditions, the TL7726 provides a forward-voltage drop of only 200 mV at 20 mA. Furthermore, the device provides symmetrical protection to both positive- and negative-going transient voltages (effectively replacing up to twelve diodes).

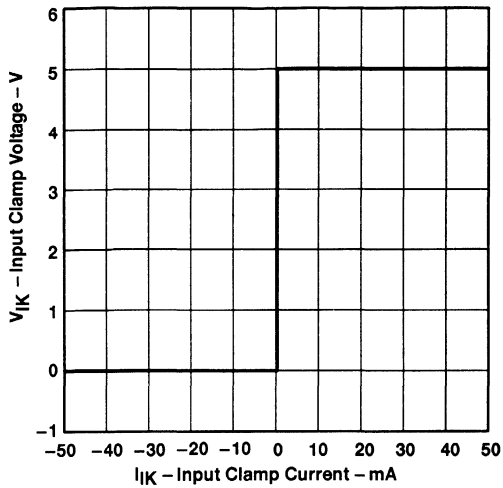
Under normal operation, the TL7726 offers a very high input impedance to ground and draws less than 10 μ A; however, under fault conditions, a low-impedance path is offered to clamp the protected node at a voltage between V_{ref} to $V_{ref} + 200$ mV and between GND to GND - 200 mV. This clamping operation is specified over the full operating temperature range.

The TL7726 is available in an 8-pin DIP (P package) or an 8-pin SOIC (D package). The TL7726C is characterized for operation from 0°C to 70°C. The TL7726I is characterized for operation from -40°C to 85°C. The TL7726Q is characterized for operation from -40°C to 125°C.

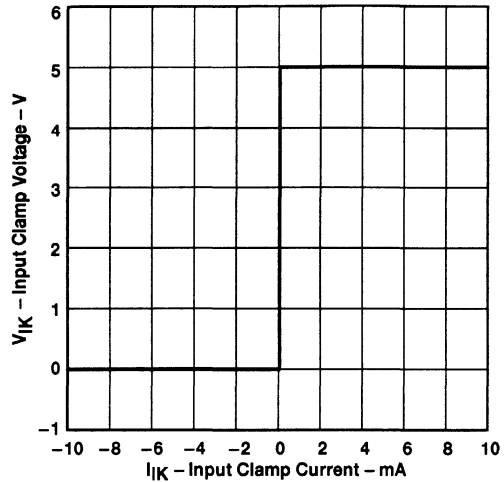
Circuit Operation

As shown in Figure 6, an internal reference voltage is generated across transistor Q1. This reference is connected as a diode is a diode forward-voltage drop more negative than the external connection REF. The current through Q1, which is determined by the resistor R1, is only a few microamps; therefore, the supply rail of the circuit to be protected (usually connected to REF) is only very slightly loaded, allowing the TL7726 to be used with battery-powered equipment. The transistor Q2 generates a reference voltage with a circuit complementary to Q1 that limits voltages more negative than GND.

The voltage to be limited is connected to CLAMP. If the voltage at this input becomes more positive than the internal reference voltage at the emitter of Q1 plus the forward voltage of the base-emitter diode of Q4, a collector current flows in Q4. This current comes in part from the base of Q3, whose collector current further increases the base current of Q4. This feedback ensures that the base current of Q5 and the collector current increase simultaneously. This circuit approach ensures that a current of only a few microamps flows in REF as long as the clamp voltage, V_{IK} , is the same as or smaller than the reference voltage, V_{ref} . A small increase of the voltage at CLAMP causes the current to increase very rapidly (see Figures 8 and 9). The circuit behaves like an external low-resistance Zener diode whose breakdown voltage can be set by a reference voltage at REF.



**Figure 8. Characteristics of the TL7726
($V_{ref} = 5\text{ V}$)**



**Figure 9. Characteristics of the TL7726
at Low Current ($V_{ref} = 5\text{ V}$)**

A complementary circuit has the effect that if the input sees a voltage that is more negative than GND, the resulting current (flowing outward) also increases very rapidly. In this voltage range, the circuit behaves like a very low resistance diode having a forward voltage of only some tenths of a millivolt.

The characteristics of the TL7726 cannot be properly represented using linear axes. Therefore, mixed log/linear axes are used (see Figure 10) so the voltage limits over a very wide range can be shown in detail.

Overvoltages at device pins are often of very short duration but of high amplitude. The hex clamping circuit must be able to provide reliable protection under these conditions, so the device has been designed such that a continuous current of 50 mA is permissible at the clamp input. However, the maximum power dissipation of the package must be taken into account in case such currents flow simultaneously into several inputs.

Extremely rapid operation of the hex clamping circuit has been achieved with the capacitor C1 (see Figure 6), which essentially consists of the collector-base (Miller) capacitance of Q5. This ensures that Q5 is immediately switched on if there are rapid voltage changes. Figure 11 shows that voltage limiting is achieved with virtually no delay. Figure 12 shows the circuit used to make these measurements. Since this circuit reacts to practically any voltage change, it must be noted that several microseconds elapse from a change of amplitude until a new stable value is reached (see Figure 13).

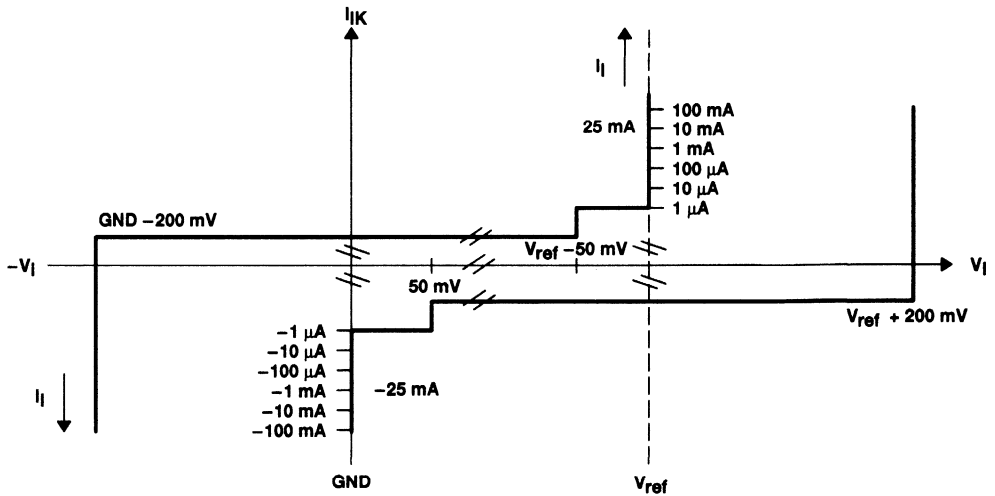


Figure 10. Current and Voltage Limits of TL7726

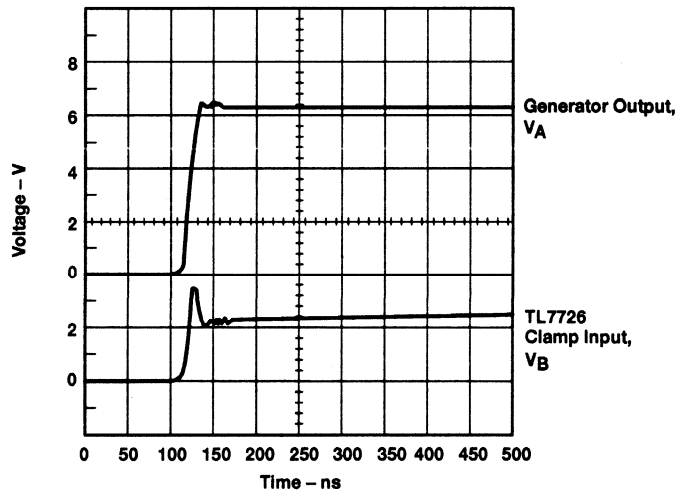


Figure 11. Behavior of TL7726 With Rapid Voltage Changes

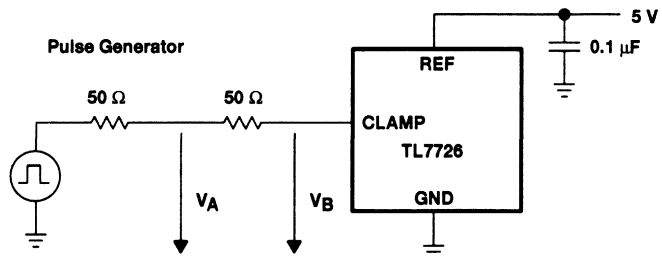


Figure 12. Measurement Circuit

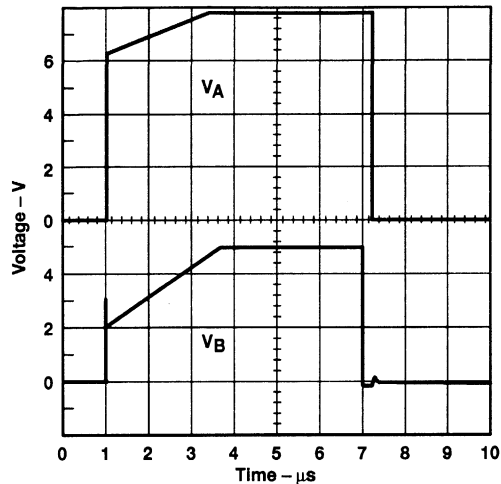


Figure 13. Settling Time at the Input of the Hex Clamping Circuit

Application Examples Using the TL7726

The TL7726 was developed to protect the inputs of linear (analog) ICs against overvoltage and to ensure the reliable operation of these components both in demanding applications and in harsh environments. A typical application of the TL7726 is extremely simple, as shown in Figure 14.

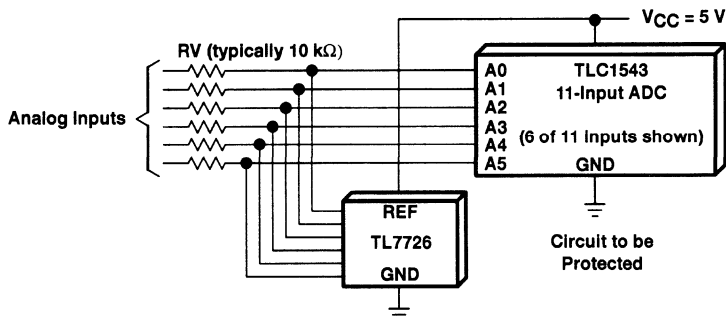


Figure 14. Typical Application of the Hex Clamping-Circuit TL7726

The TL7726 is ideal for protecting the inputs of the TI range of multiple input analog-to-digital converters. The TL7726 can reliably handle currents up to 50 mA. The series current-limit resistor (RV) is chosen to limit the current to this level. The clamp voltage level is set to be within 200 mV of V_{ref} and GND.

The reference voltage pin (REF) of the hex clamping circuit is connected to the supply voltage (V_{CC}) of the circuit to be protected whose inputs are connected to the CLAMP inputs (see Figure 14). The requirement for series resistors depends on the particular application. If the input signal to be limited is supplied by a comparatively high-impedance source, and if only undefined currents must be prevented from flowing into the substrate of the circuit to be protected, such resistors are not needed. However, in most cases, voltages of considerable amplitude can be expected. These are coupled into the signal inputs and cause significant interference. In such cases, the TL7726 should also be protected against damage; this can only be ensured if the current that flows can be limited to an acceptable amount with a series resistor. The TL7726 reliably diverts currents up to ± 50 mA where the difference of the voltage between the input voltage (V_{IK}) and the reference voltage (depending on whether current is flowing to REF or GND) is only a few hundred millivolts. The RV series resistor can be chosen over a wide range depending on the requirements of the circuit to be protected. Resistors from a few tens of ohms up to several tens of kilohms (i.e., 20Ω to $40 \text{ k}\Omega$) can be used.

When choosing series resistors used to limit current flowing into the TL7726, consideration should be given to the maximum power dissipation [$P_{D(max)}$] that the TL7726 can withstand. The limiting factors are the maximum permissible device temperature of 150°C and the thermal resistance ($R_{\theta JA}$) between the device and ambient temperature. The following expression applies (see the TL7726 data sheet):

$$P_{D(max)} = \frac{150^{\circ}\text{C} - T_A}{R_{\theta JA}}$$

where:

T_A = ambient temperature

$R_{\theta JA}$ (D package) = $172^{\circ}\text{C}/\text{W}$

$R_{\theta JA}$ (P package) = $105^{\circ}\text{C}/\text{W}$

given the following derating factors

Derating factor (D package) = $1/R_{\theta JA} = 5.8 \text{ mW}/^{\circ}\text{C}$

Derating factor (P package) = $1/R_{\theta JA} = 9.5 \text{ mW}/^{\circ}\text{C}$

Current Flow

Consideration should be given to the path taken by the current that flows into the TL7726. A positive current flowing into a CLAMP terminal is channeled to GND (see Figure 6 and Figure 15); similarly, a negative current flows to REF. Since REF is normally connected to the V_{CC} rail supplying other circuits, this voltage source must be able to withstand the current flow. In most cases, only short duration voltages need to be limited; this usually means that the filter capacitor in the power supply must be of sufficiently large capacitance and the ground return of sufficiently large size to prevent excessive ground bounce.

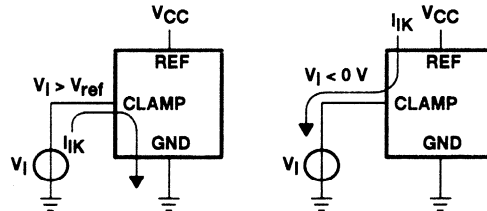


Figure 15. Current Flow Paths

Summary

Until recently, the protection of analog circuits in harsh environments where the inputs could be subjected to undefined overvoltages was only possible with considerable extra circuitry. Although this circuitry gave protection against destruction, it often limited the performance of the protected device. The availability of the TL7726 hex clamping circuit now provides both reliable and transparent protection operation for up to six analog inputs in a single package.

***Microcontroller Based Data
Acquisition Using the TLC2543
12-Bit Serial-Out ADC***

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Introduction

Scope of this Application Report

This application report describes how to construct 12-bit data acquisition systems using the TLC2543 serial-out analog-to-digital converter (ADC) in conjunction with a range of four popular microcontrollers.

The four microcontrollers used are the TMS370, H8/300, 68HC11 and 80C51.

The TLC2543

The TLC2543 is a 12-bit ADC which uses the switched capacitor successive approximation technique to perform the conversion process and provides a maximum sampling rate of 66k samples per second (KSPS) while using only 1 mA (typical) of supply current.

The block diagram of the TLC2543 is shown in Figure 1. Any one of eleven analog input channels can be selected by programming the four most significant bits (MSBs) of the eight bit channel/mode control byte applied serially to the DATA INPUT terminal of the device. In addition three internal test voltages [V_{ref-} , V_{ref+} and $(V_{ref+} - V_{ref-})/2$] can be applied to the converter for calibration or other purposes by applying the appropriate code to the same four MSBs.

The four least significant bits (LSBs) of the channel/mode control byte are used to select the output data length (8, 12 or 16 bits), the output data order (MSB first or LSB first) and whether unipolar (binary) or bipolar (2's complement around $(V_{ref+} - V_{ref-})/2$) format is required.

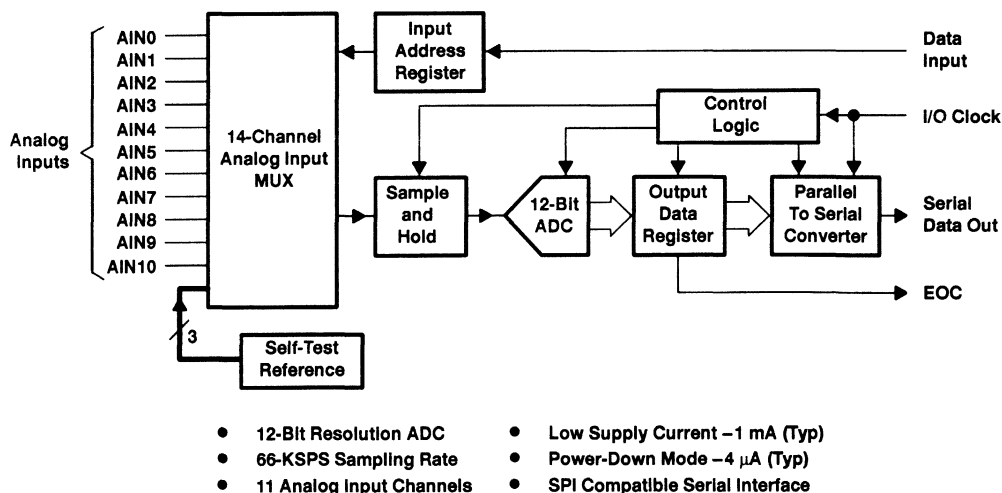


Figure 1. TLC2543 Block Diagram

Interface Timing

Four transfer methods are available for obtaining the full 12 bits of resolution from the TLC2543. Either 12 or 16 clock cycles can be used for each conversion and data transfer.

A chip select (\overline{CS}) pulse can be inserted at the start of each conversion or only once at the beginning of each sequence of conversions with \overline{CS} remaining low until the sequence is completed.

Figure 2 shows the timing for the method which uses 16 clock cycles for each conversion and data transfer cycle and which inserts \overline{CS} between each of these transfer cycles. Figure 3 shows the timing for the method which uses 16 clock cycles for each conversion and data transfer cycle but inserts \overline{CS} only once at the start of each sequence of conversions.

This application report describes various microcontroller interfaces, each of which uses 16 clock cycles for each conversion data transfer. \overline{CS} is applied at the start of each conversion and data transfer. This method allows for the general case where one or more conversions may be required. It also simplifies the required software.

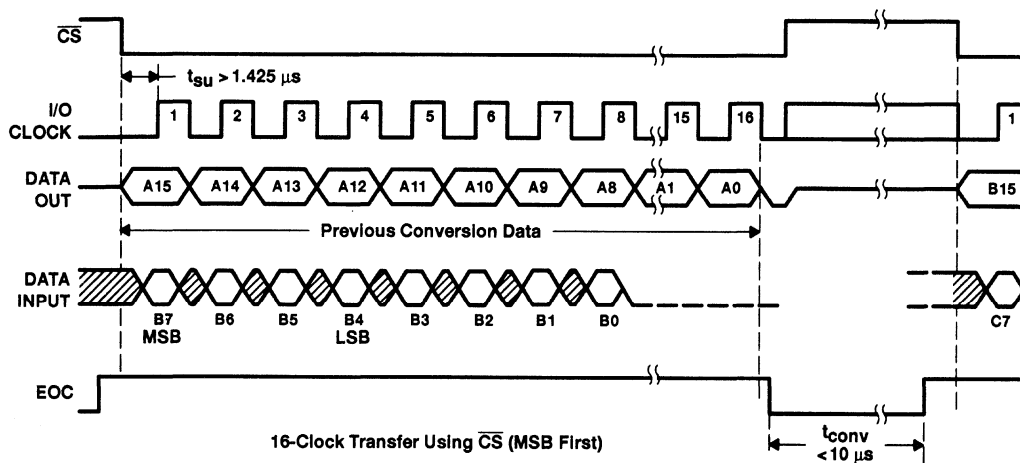


Figure 2. Timing for 16-Clock Transfer Using \overline{CS} With MSB First

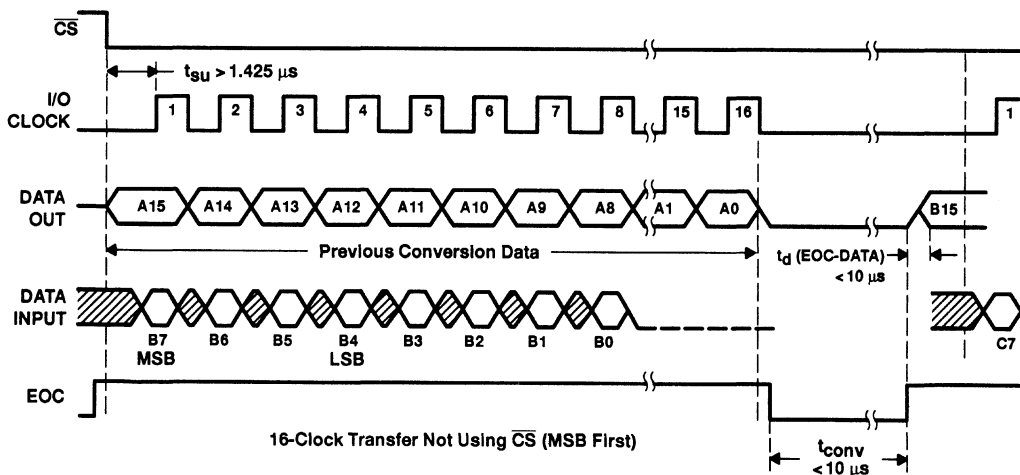


Figure 3. Timing for 16-Clock Transfer Not Using \overline{CS} With MSB First

Minimum Number of Data Transfers per Channel

It should be noted that in any single data transfer cycle between the TLC2543 and the chosen microcontroller the data output from the ADC is the result of the previous conversion. The software listings included in this application report have been written for the general case where the conversion results may be required for any individual channel or sequence of channels. In this case the program included for each microcontroller interface must be run at least twice per channel so that valid data corresponding to the required analogue input channel and ADC mode is delivered.

Software can be written to implement the consecutive channel scanning mode of operation of the TLC2543. In this case the result from the first analog-to-digital conversion should be ignored or overwritten.

Serial Peripheral Interface (SPI)

The fastest and most efficient method of implementing a data transfer between the TLC2543 and a microcontroller is to use the serial peripheral interface (SPI) of the microcontroller, if this is available.

The TMS370 (Texas Instruments), H8/300 (Hitachi) and MC68HC11 (Motorola) all offer SPIs (or the equivalent) in a subset of each of these families of microcontrollers. The H8/300 offers a serial communications interface (SCI) which can be configured to operate in a similar way to that of the standard SPI's offered by the TMS370 and MC68HC11.

The principle features of the SPI are:

- Simultaneous serial data input and output
- Synchronous operation
- Provision of frequency programmable serial clock
- Data transfer complete flag

Figure 4 shows the structure of the SPI. In this case the TMS370C010 is used to illustrate the main elements of the interface.

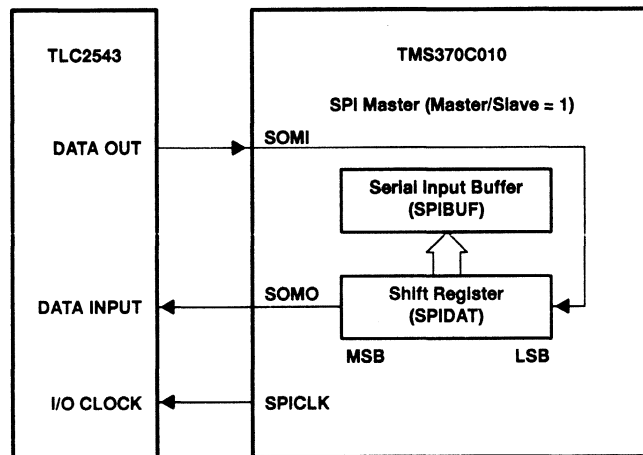


Figure 4. Serial Peripheral Interface – Internal Structure and Data Flow

The microcontroller can be configured by software to perform as the SPI master or slave. When operating as the master, data is input to the SPI shift register (SPIDAT) via the slave out master in (SOMI) terminal. At the same time data is output from the SPIDAT via the slave in master out (SOMO) terminal.

The SPI functions as follows. The SPIDAT should be loaded with the first byte of data to be sent. This automatically initiates the transmission of this byte. During this transmission time data is received at the other end of the SPIDAT shift register. The SPI INT FLAG is regularly checked. As soon as the last bit of the input data byte is received the SPI INT FLAG is set to 1. This then signals that the received byte can be read from the serial input buffer (SPIBUF) and that the SPIDAT is ready to accept the next byte of data to be transmitted.

Additional SPI features which apply to the specific microcontrollers are described in their respective sections which follow.

TLC2543 to SPI Interface Timing

The timing digram for the 16 clock transfer TLC2543 to SPI interface is shown in Figure 5. The channel select/mode data is read into the TLC2543 on the positive going edges of the I/O clock and analog-to-digital conversion results are read into the microcontroller on the negative going edges of the I/O clock.

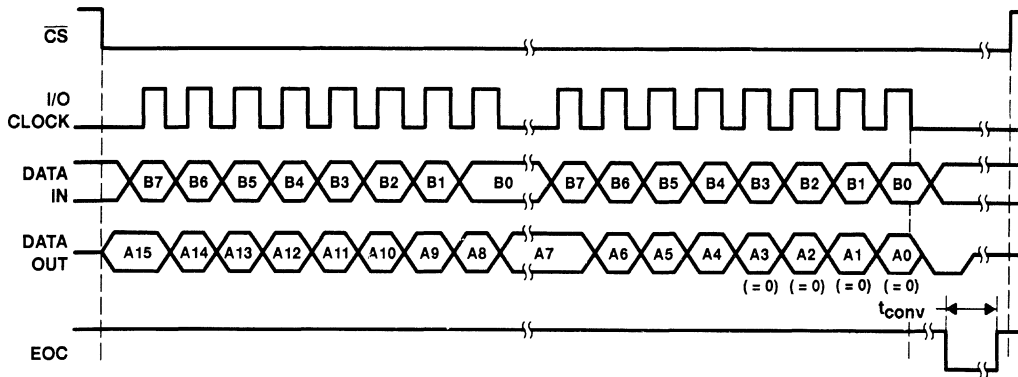


Figure 5. TLC2543 to SPI Interface Timing

Software Flowcharts

Figures 6, 7, and 8 show the flow charts for the main program and subroutines used in the TLC2543 to TMS370C010 interface software shown in this application report. The same program structure also applies to the other three interfaces included in this report.

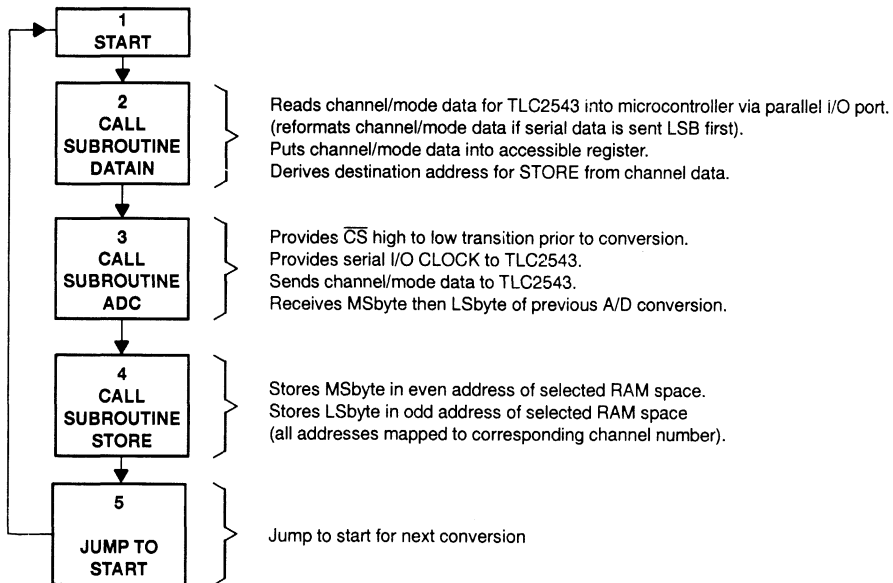


Figure 6. Flowchart for Main Program of TLC2543 to TMS370C010

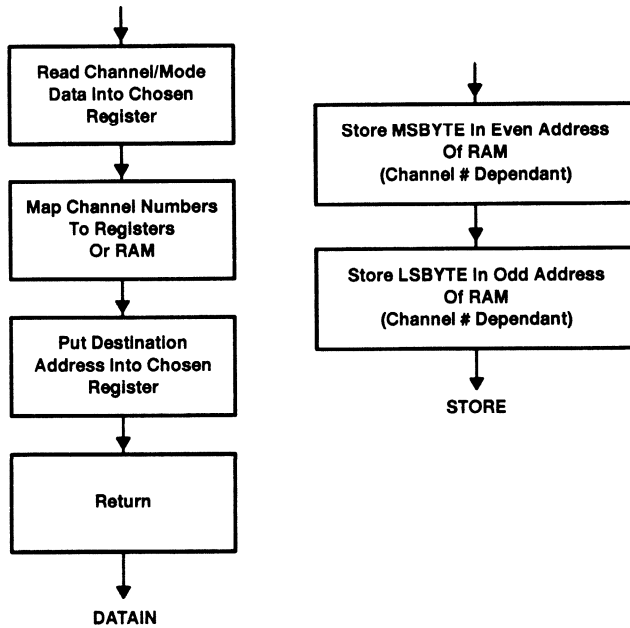


Figure 7. Flowcharts of Subroutine DATAIN and STORE for TLC2543 to TMS370C010 Interface Software

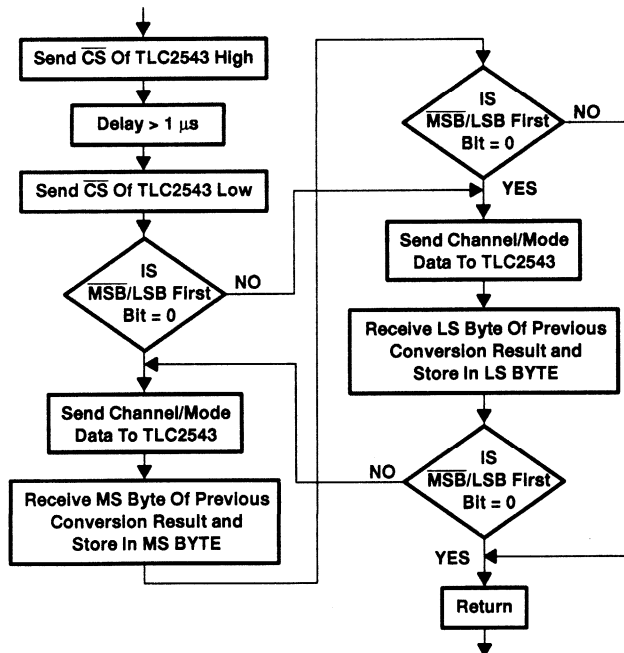


Figure 8. Flowcharts of Subroutine ADC for TLC2543 to TMS370C010 Interface Software

TLC2543 TO TMS370 Microcontroller Interface

Microcontroller Features

Within the family of TMS370 microcontrollers there are several versions which contain a serial peripheral interface (SPI) facility. One of these versions should be chosen to implement the interface method described below. One such version is the TMS370C010 which is used to illustrate the method.

Interface Circuit

Figure 9 shows the circuit interconnections for the TLC2543 to TMS370C010 microcontroller interface. Note that no extra logic is required to implement this interface.

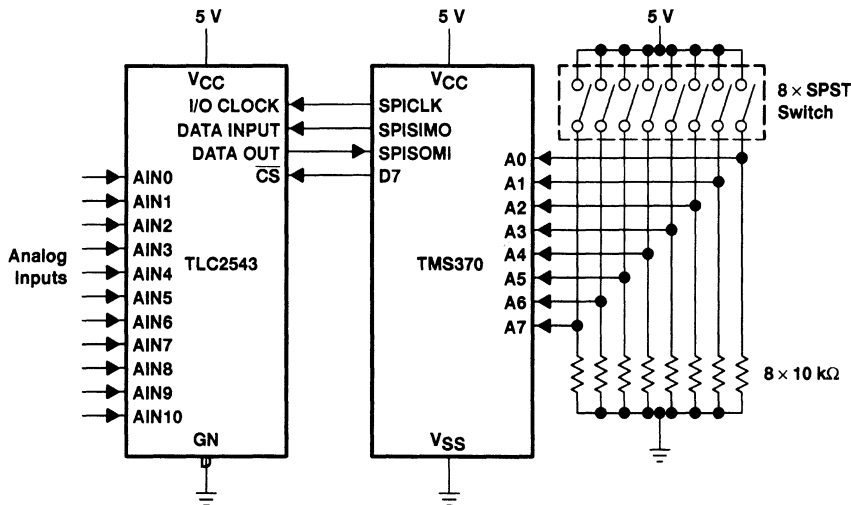


Figure 9. TLC2543 to TMS370C010 Interface Circuit

Depending upon the layout of the particular printed circuit board used it may be necessary to insert a small value capacitor of between 50 and 100 pF between the I/O CLOCK input of the TLC2543 and ground. This has the effect of ensuring that data applied to the DATA INPUT terminal of the TLC2543 is valid before the positive going transition of the I/O CLOCK.

The positive reference, REF+, to the TLC2543 is provided directly from the V_{CC+} supply.

The four digital interface terminals, I/O CLOCK, DATA INPUT, DATA OUT, and \overline{CS} , of the TLC2543 connect directly to the SPICLK, SPISIMO, SPISOMI and D7 terminals respectively of the TMS370C010.

The operation mode and channel number of the TLC2543 is determined by the serial data which is sent to its DATA INPUT terminal.

Software

List 1 contains the software listing for the program which controls the interface illustrated in Figure 5. The software consists of the main program and three subroutines called DATA IN, ADC and STORE. DATAIN reads in the channel select and mode control data into a holding register and maps the channel select number to a corresponding pair of registers between R64 and R91. The mapping vector is held in register R10. ADC provides the chip select pulse, controls the SPI operation, and puts the MSByte and LSByte of each conversion result into registers R20 and R21 respectively. STORE puts the MSByte into the even number register and the LSByte into the odd number register mapped by the contents of register R10.

List 1 (Continued)

LINE	LOC	OBJ	SOURCE
61	402b	'00d3	JMP START
62			
63			;
64			;Subroutine :- DATAIN
65			;
66	402d	9122	DATAIN MOV ADATA,B ;Read ADC mode/channel
67	402f	d10b	MOV B,R11 ;Put ADC mode/channel
68			;in R11
69	4031	53f0	AND #0F0H,B ;Retain channel number
70	4033	cc	RR B ;* * * * *
71	4034	cc	RR B ;* Map channel numbers *
72	4035	cc	RR B ;* to registers R64-R91 *
73	4036	cc	RR B ;* R10 contains storage *
74	4037	5c02	MPY #002,B ;* address *
75	4039	5840	ADD #40H,B ;* Even numbers - MS Byte*
76	403b	d10a	MOV B,R10 ;* Odd numbers - LS Byte *
77			;* * * * *
78	403d	f9	RTS
79			;
80			;Subroutine :- ADC
81			;
82	403e	2203	ADC MOV #003H,A
83	4040	a4802e	SBIT1 CSBIT ;Set ADC Chip Select high.
84	4043	b2	LOOP1 DEC A ;Chip Select stays high
85	4044	'06fd	JNE LOOP1 ;while A is not 0.
86	4046	c5	CLR B
87	4047	512e	MOV B,DDATA ;CS goes low
88	4049	2207	MOV #7,A
89	404b	2131	MOV A,SPICTL ;Enable SPI transmission
90	404d	'76020b19	JBIT1 MSLSB,LS1ST
91	4051	120b	MOV R11,A
92	4053	2139	MOV A,SPIDAT
93			MOV R11,SPIDAT ;Send mode/channel data
94			;to TLC2543
95	4055	'a74031fc	FLAG1 JBIT0 SPIF,FLAG1;If SPIF=0, repeat check.
96	4059	a21437	MOV SPIBUF,R20 ;Put received MS Byte
97			;in R20
98	405c	71390b	MOV R11,SPIDAT ;Send mode/channel data
99			;to TLC2543
100	405f	'a74031fc	FLAG2 JBIT0 SPIF,FLAG2;If SPIF=0, repeat check.
101	4063	a21537	MOV SPIBUF,R21 ;Put received LS Byte
102			;in R21
103	4066	'77020b32	JBIT0 MSLSB,RETURN ;If MSLSB=0, go
104			;to RETURN
105	406a	120b	LS1ST MOV R11,A
106	406c	2139	MOV A,SPIDAT
107	406e	'a74031fc	FLAG3 JBIT0 SPIF,FLAG3;If SPIF=0, repeat check.
108	4072	a21537	MOV SPIBUF,R21 ;Put received LS Byte
109			;in R21
110	4075	120b	MOV R11,A
111	4077	2139	MOV A,SPIDAT
112	4079	'a74031fc	FLAG4 JBIT0 SPIF,FLAG4;If SPIF=0, repeat check.
113	407d	a21437	MOV SPIBUF,R20 ;Put received MS Byte
114			;in R20
115	4080	2208	MOV #08,A ;* * * * *
116	4082	d516	CLR R22 ;*
117	4084	dd14	RRC R20 ;* Reformat MS Byte *
118	4086	df16	RLC R22 ;*
119	4088	b2	DEC A ;* Put result in R20 *
120	4089	'06f9	JNZ LOOP2 ;*
121	408b	421614	MOV R22, R20 ;* * * * *
122	408e	2208	MOV #08,A ;* * * * *
123	4090	d517	CLR R23 ;*
124	4092	dd15	RRC R21 ;* Reformats LS Byte *
125	4094	df17	RLC R23 ;*
126	4096	b2	DEC A ;* Put result in R21 *
127	4097	'06f9	JNZ LOOP3 ;*
128	4099	421715	MOV R23,R21 ;* * * * *

List 1 (Continued)

LINE	LOC	OBJ	SOURCE
129	409c	f9	RETURN RTS
130			;
131			;Subroutine :- STORE
132			;
133	409d	1214	STORE MOV R20,A ;Put MS Byte into even
134	409f	9b0a	MOV A,@R10 ;address contained in R10
135	40a1	d30a	INC R10 ;(R10)+1
136	40a3	1215	MOV R21,A ;Put LS Byte into odd
137	40a5	9b0a	MOV A,@R10 ;address contained in R10
138	40a7	f9	RTS
139			.END

Opto-Isolated 12-Bit Data Acquisition System

The serial nature of the data flow between the TLC2543 analog-to-digital converter and the accompanying microcontroller makes this ADC an ideal choice for isolated 12-bit data acquisition. Figure 10 shows an opto-isolated system which uses four optocouplers to provide a 3-kV isolation barrier.

Note that the optocoupler which routes conversion result data from the TLC2543 to the microcontroller is a single device and does not share the same piece of silicon with any of the other optocouplers used. This ensures that the full 3 kV of isolation is maintained between the ADC and microcontroller.

The choice of VP0610 P-channel enhancement MOSFETs avoids the use of an extra inverter stage for each optocoupler driver. In addition, the relatively low input capacitance of the VP0610 (typically 15 pF) allows data rates up to 100 kHz to be achieved without the need for external buffers to be added at the outputs of the TLC2543 and TMS370.

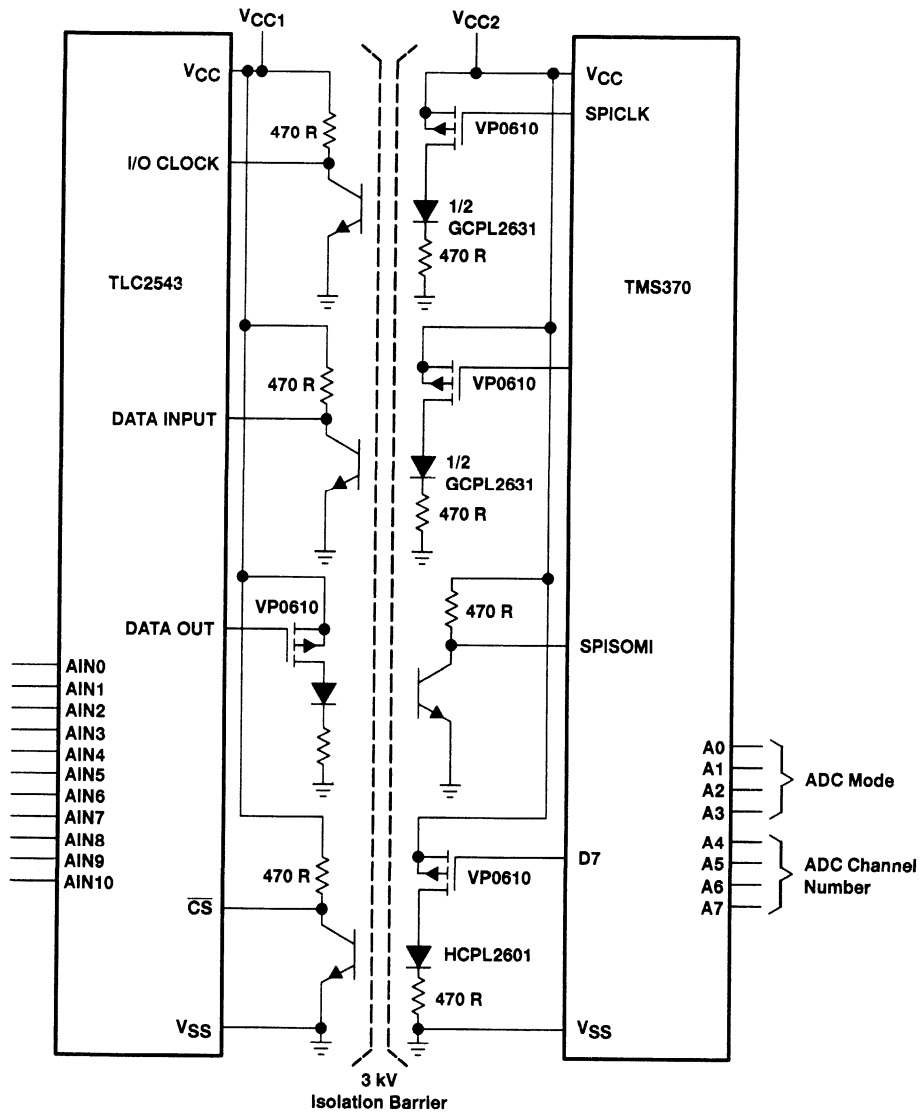


Figure 10. Opto-Isolated 12-Bit Data Acquisition System

TLC2543 to H8/325 Microcontroller Interface

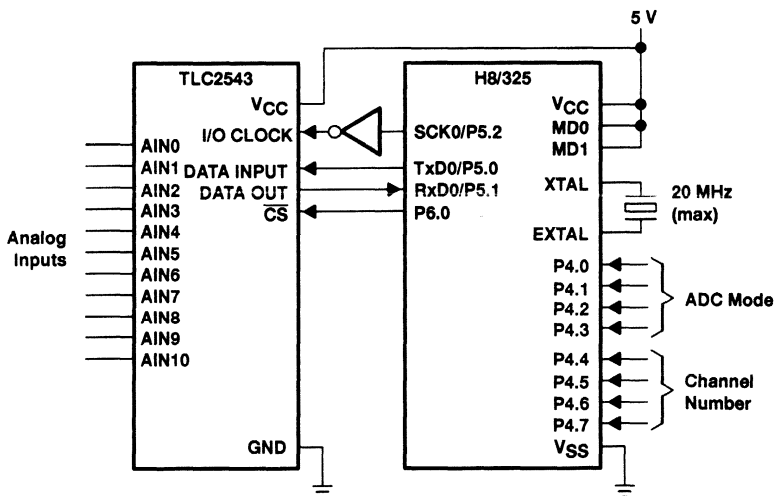
Microcontroller Features

The individual members of the H8 family of microcontrollers can be differentiated by various criteria, for example the inclusion or otherwise of an on-board 8-bit resolution analog-to-digital converter (ADC). Those members which include an ADC generally cost between 10 and 20 percent more than their counterparts which do not.

System requirements such as ADC resolution, remote location of ADC, flexibility, and total cost all influence the final choice of microcontroller architecture. The H8/325, used for this application report, does not include an on-board ADC but provides 1K of RAM, 32K of ROM, and two serial I/O ports. It is therefore well suited to interfacing with the TLC2543 serial output ADC.

Interface Circuit

Figure 11 illustrates a typical 12-bit data acquisition system which uses the H8/325 microcontroller to coordinate the operation of the TLC2543 ADC via one of its serial (SCI) ports. The circuit uses the H8's 8-bit parallel I/O port 4 to route ADC channel and mode information into the microcontroller. This information could be provided by a host system data bus or, as in Figure 6, by a bank of eight manually operated toggle switches situated on the same printed circuit board as the microcontroller.



NOTE: Single Chip Mode (MD0 = MD1 = 1)

Figure 11. TLC2543 to H8/300 Microcontroller Interface Circuit

Software

List 2 shows the program which was written to coordinate the interface. It uses three subroutines to implement the overall interface to the TLC2543. The first of these is called DATAIN which reads ADC channel and mode information into the microcontroller. It also maps converter channel numbers to corresponding addresses in RAM where conversion results can be stored. In this case the addresses from 0040H to 0067H were chosen to store the results. The most significant byte of each result is placed in an even address and the least significant byte of each result is placed in the corresponding adjacent odd address.

The conversion result of each channel is stored in left justified format and therefore occupies the upper 12 bits of the 16-bit words which occupy even addresses from 0040H up to 0066H.

The second subroutine to be used is ADC. This begins by producing a chip-select high pulse. The trailing negative edge of this pulse is rapidly followed by the transmission of channel and mode information to the converter.

List 2

```

LINE  LOC  OBJ  SOURCE
1      ; * * * * *
2      ; *
3      ; *      TLC2543 to H8 Microcontroller Interface Program.
4      ; *
5      ; * This program contains subroutines DATAIN, ADC,
6      ; * FORMAT and STORE.
7      ; * DATAIN reads channel number and mode data into the
8      ; * microcontroller via Port4. "ADC" controls A to D
9      ; * conversion. "FORMAT" changes conversion results from
10     ; * LSB first format to MSB first format. "Store" places
11     ; * results in memory addresses 40 to 5B (MS Bytes in even
12     ; * addresses, LS Bytes in odd addresses) according to
13     ; * channel number.
14     ; * * * * *
15     ;
16     ; * Define special function register names *
17     ;
18     FFDD      RDR      EQU H'FFDD      ;Receive Data Register - RDR
19     FFDB      TDR      EQU H'FFDB      ;Transmit Data Register - TDR
20     FFD8      SMR      EQU H'FFD8      ;Serial Mode Register - SMR
21     FFDA      SCR      EQU H'FFDA      ;Serial Control Register - SCR
22     FFDC      SSR      EQU H'FFDC      ;Serial Status Register - SSR
23     FFD9      BRR      EQU H'FFD9      ;Bit Rate Register - BRR
24     FFB8      P5DDR     EQU H'FFB8      ;Port5 Data Direction Register
25     FFBA      P5DR      EQU H'FFBA      ;Port5 Data Register - P5DR
26     FFB5      P4DDR     EQU H'FFB5      ;Port4 Data Direction Register
27     FFB7      P4DR      EQU H'FFB7      ;Port4 Data register - P4DR
28     FFB9      P6DDR     EQU H'FFB9      ;Port6 Data Direction register
29     FFB6      P6DR      EQU H'FFB6      ;Port6 Data Register
30
31
32     1000      ORG H'1000      ;Sets start of program
33     ;
34     ; * Main Program *
35     ;
36     1000 79001000      MOV.W #H'1000, R0
37     ;
38     1004 7907FD00      MOV.W R0, @H'0000      ;Sets reset vector to START
39     1008 F984      START  MOV.W #H'FD00, SP      ;Sets contents of Stack Pointer
40     100A 39D8      MOV.B #H'84, R1L      ; * * * * *
41     100C F931      MOV.B R1L, @SMR:8      ; * Sets up serial port
42     100E 39DA      MOV.B #H'31, R1L      ; * registers for simultaneous
43     1010 F901      MOV.B R1L, @SCR:8      ; * transmit and receive
44     1012 39D9      MOV.B #H'01, R1L      ; *
45     1014 F901      MOV.B R1L, @BRR:8      ; * * * * *
46     1016 6A89FFB9      MOV.B R1L, @P6DDR     ;Sets R1(Low Byte) to 01H
47     101A 5E001082      JSR @DATAIN:16        ;Set Bit0 of Port6 as Output
48     101E 5E00102C      JSR @ADC:16           ;Read in ADC channel/mode data
49     1022 5E0010B4      JSR @FORMAT:16        ;Do A/D conversion
50     1026 5E0010AC      JSR @STORE:16         ;Reformat A/D conversion result
51     102A 40DC      BRA START             ;Store A/D conversion result
52     ;
53     ; * Subroutine ADC which controls the conversion process *
54     ;
55     102C FA05      ADC      MOV.B #H'05, R2L      ;Put 05 in R2L
56     102E 7FBB7000      BSET #0, @P6DR:8      ;TLC2543 chip select goes high
57     1032 1A0A      CSHIGH  DEC R2L              ;(R2L) - 1
58     1034 46FC      BNE CSHIGH            ;If not zero, CS stays high
59     1036 7FBB7200      BCLR #0, @P6DR:8      ;TLC2543 chip select goes low
60     103A 6A0CFFB7      MOV.B @P4DR, R4L      ;Puts channel/mode data in R4L
61     103E 731C      BTST #1, R4L          ;Is LSBF of channel/mode data
62     1040 461E      BNE LSBYTE            ;If not, do LSBYTE first
63     1042 7EDC7370      MSBYTE  BTST #7, @SSR:8      ;Is TDR empty ?
64     1046 47FA      BEQ MSBYTE            ;If not empty, repeat check.
65     1048 34DB      MOV.B R4H, @TDR:8     ;Put channel/mode data in TDR
66     104A 7FDC7270      BCLR #7, @SSR:8      ;Reset TDRE bit of SSR to 0
67     104E 7EDC7360      TESTB61 BTST #6, @SSR:8 ;Is receive shift reg. empty ?

```

List 2 (Continued)

LINE	LOC	OBJ	SOURCE	
68	1052	47FA	BEQ TESTB61	;If not empty, repeat check
69	1054	23DD	MOV.B @RDR:8, R3H	;Put MS Byte of conversion
70				;result in R3H
71	1056	7FDC7260	BCLR #6, @SSR:8	;Reset RDRF bit of SSR to 0
72	105A	68D3	MOV.B R3H, @R5	;Put MS Byte in even address
73				;mapped by channel number.
74	105C	731C	BTST #1, R4L	;Is LSBF of channel/mode data 0
75	105E	4620	BNE RETURN	;If not, return from subroutine
76	1060	7EDC7370	LSBYTE BTST #7, @SSR:8	;Is TDR empty ?
77	1064	47FA	BEQ LSBYTE	;If not empty, repeat check
78	1066	34DB	MOV.B R4H, @TDR:8	;Put channel/mode data in TDR
79	1068	7FDC7270	BCLR #7, @SSR:8	;Reset TDRE bit of SSR to 0
80	106C	7EDC7360	TESTB62 BTST #6, @SSR:8	;Is receive shift reg. empty ?
81	1070	47FA	BEQ TESTB62	;If not empty, repeat check
82	1072	0A0D	INC R5L	; (R5L) + 1
83	1074	2BDD	MOV.B @RDR:8, R3L	;Put LS Byte of conversion
84				;result in R3L
85	1076	7FDC7260	BCLR #6, @SSR:8	;Reset RDRF bit of SSR to 0
86	107A	68DB	MOV.B R3L, @R5	;Put LS Byte in odd address
87				;mapped by channel number.
88	107C	731C	BTST #1, R4L	;Is LSBF of channel/mode data 0
89	107E	46C2	BNE MSBYTE	;If not, go to MSBYTE
90	1080	5470	RETURN RTS	;Return from subroutine
91				
92				; * Subroutine "DATAIN" which reads in ADC channel/mode data *
93				
94	1082	79040000	DATAIN MOV.W #H'0000, R4	
95	1086	79050000	MOV.W #H'0000, R5	
96	108A	6A0CFB7	MOV.B @P4DR, R4L	; Puts channel/mode data in R4L
97	108E	0CCD	MOV.B R4L, R5L	; Puts (R4L) in R5L
98	1090	110D	SHLR R5L	* * * * * * * * * *
99	1092	110D	SHLR R5L	; * Retain only channel * *
100	1094	110D	SHLR R5L	; * number in R5L * *
101	1096	110D	SHLR R5L	* * * * * * * * * *
102	1098	79060002	MOV.W #0002, R6	; * * * * * * * * * *
103	109C	50E5	MULXU R6L, R5	; * Maps channel numbers to * *
104	109E	8D40	ADD.B #H'40, R5L	; * even addresses 40H to 5AH* *
105				; * Put address in R5L * *
106				* * * * * * * * * *
107	10A0	F008	MOV.B #H'08, R0H	; Put 08 in R0H
108	10A2	110C	NEXTBIT SHLR R4L	; * * * * * * * * * *
109	10A4	1204	ROTXL R4H	; * Reformats channel/mode data* *
110	10A6	1A00	DEC R0H	; * from MSB first to LSB first* *
111	10A8	46F8	BNE NEXTBIT	* * * * * * * * * *
112	10AA	5470	RTS	
113				
114				; * Subroutine "STORE" stores A/D conversion results in RAM *
115				
116	10AC	68D3	STORE MOV.B R3H, @R5	;Store MS Byte in even address
117				;corresponding to channel
118				;number
119	10AE	0A0D	INC R5L	; (R5) + 1
120	10B0	68DB	MOV.B R3L, @R5	;Store LS Byte in odd address
121				;corresponding to channel
122				;number
123	10B2	5470	RTS	;Return from subroutine
124				
125				; * Subroutine "FORMAT" changes received data format * *
126				; * (LSB first) into MSB first format * *
127				
128	10B4	F008	FORMAT MOV.B #H'08, R0H	; Put 08 in R0H
129	10B6	1103	LOOP1 SHLR R3H	; * * * * * * * * * *
130	10B8	1207	ROTXL R7H	; *
131	10BA	1A00	DEC R0H	; * Reformats MSBYTE * *
132	10BC	46F8	BNE LOOP1	; *
133	10BE	0C73	MOV.B R7H, R3H	; * * * * * * * * * *
134	10C0	F008	MOV.B #H'08, R0H	; Put 08 in R0H
135	10C2	110B	LOOP2 SHLR R3L	; * * * * * * * * * *

List 2 (Continued)

LINE	LOC	OBJ	SOURCE		
136	10C4	120F	ROTXL R7L	;	*
137	10C6	1A00	DEC R0H	;	*
138	10C8	46F8	BNE LOOP2	;	*
139	10CA	0CFB	MOV.B R7L, R3L	;	*
140	10CC	5470	RTS	;	*
141	10CE		END	;	*

TLC2543 to MC68HC11 Microcontroller Interface

Microcontroller Features

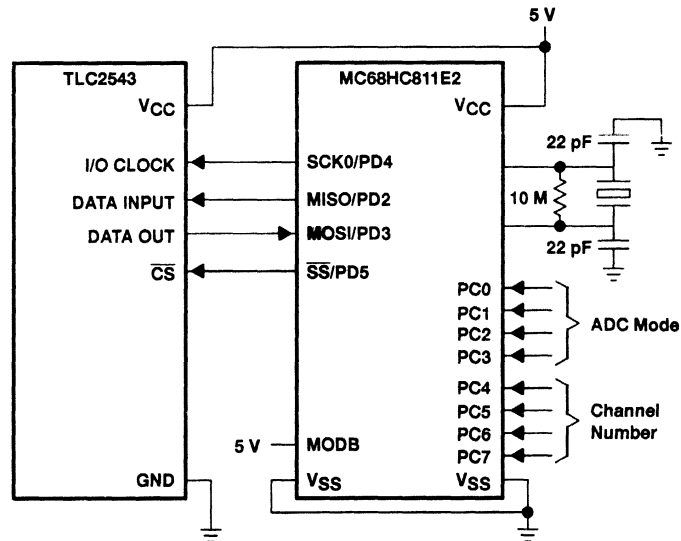
All members of the MC68HC11 family of microcontrollers contain an SPI. As is the case for the TMS370, the user is able to set the idle level of the serial clock of the 68HC11. This eliminates the need for an external inverter to be used to invert the microcontroller's serial clock output prior to its arrival at the TLC2543's serial clock input.

The 68HC11D0, 68HC11D3 and 68HC711D3 versions do not contain an on-board ADC. One of these three devices may prove to be the most cost effective choice when used with the TLC2543. All other versions contain either an 8- or 10-bit resolution ADC.

Interface Circuit

Figure 12 shows the circuit diagram of the interface between the 68HC11 and the TLC2543. The microcontroller device type used to illustrate this interface is the 48-pin dual-in-line version of the MC68HC811E2.

The master in slave out (MISO), master out slave in (MOSI) and serial clock (SCK) terminals of the SPI are available as the alternative, user selectable, functions of port D pins PD2, PD3, and PD4 respectively. When the SPI is configured to operate as a master, the $\overline{SS}/PD5$ terminal can be used as an output to drive the chip select (\overline{CS}) terminal of the TLC2543. This leaves all other bidirectional I/O ports of the microcontroller uncommitted and available for other uses. Note that no extra glue logic is required to implement the interface.



- NOTES: A. Configured for single chip mode of operation
B. Maximum SPI data rate = crystal frequency/8

Figure 12. TLC2543 to MC68HC811E2 Microcontroller Interface

Software

The listing of the program which was written to coordinate and control the interface between the TLC2543 and the 68HC811E2 is shown in List 3. The software consists of the main program and two subroutines named TLC2543 and STORE. TLC2543 begins by providing the ADC's chip select pulse. It then reads in channel/mode data via the port C parallel I/O port and subsequently sends this data to the TLC2543 via the MOSI terminal of the SPI. At the same time, the first byte of the result from the previous analog-to-digital conversion is received at the MISO terminal of the SPI.

List 3 (Continued)

LINE	LOC	OBJ	SOURCE
69	A		* If MSB/LSB-first bit = 1 go to MSB
70	A	F849 39	RETURN RTS
71	A		*
72	A		* S'routine stores MSByte in even address
73	A		* LSByte in odd address
74	A		* Channel 0 result in \$30 and \$31
75	A		* Channel 1 result in \$32 and \$33 etc.
76	A		* (Reserve addresses \$30-\$4B for results
77	A		* of all channels)
78	A	F84A A603	STORE LDAA PORTC,X
79	A	F84C CE0030	LDX #\$30
80	A	F84F 97F2	STAA TEMP
81	A	F851 86F0	LDAA #\$F0
82	A	F853 94F2	ANDA TEMP
83	A	F855 46	RORA
84	A	F856 46	RORA
85	A	F857 46	RORA
86	A	F858 46	RORA
87	A	F859 16	TAB
88	A	F85A 8602	LDAA #\$02
89	A	F85C 3D	MUL
90	A	F85D DDF2	STD TEMP
91	A	F85F 96F0	LDAA MSBYTE
92	A	F861 A7F2	STAA TEMP,X
93	A	F863 08	INX
94	A	F864 96F1	LDAA LSBYTE
95	A	F866 A7F2	STAA TEMP,X
95	A	F866 A7F2	STAA TEMP,X
96	A	F868 39	RTS
97	A		END

TLC2543 to 80C51 Microcontroller Interface

Microcontroller Features

The 80C51 microcontroller family does not provide an SPI or equivalent facility. In order to implement the interface with the TLC2543 analog-to-digital converter, it is necessary to use software to synthesize the operation of an SPI. This results in a slower data transfer rate which is governed by the microcontroller's instruction cycle times. These are, in turn, influenced by the clock frequency of the microcontroller. The highest clock frequency possible should therefore be selected for the microcontroller to minimize instruction cycle times and thus optimize the data transfer rate of the interface.

Interface Circuit

Figure 13 shows the circuit for the interface of the TLC2543 to the 80C51 microcontroller. The I/O CLOCK, DATA INPUT and \overline{CS} inputs to the TLC2543 are provided via the bidirectional parallel port 1 terminals P1.0, P1.1, and P1.3 respectively. Conversion result data from the TLC2543 is received by the 80C51 through the P1.2 terminal of port 1. The channel select/mode data is input to the microcontroller via port 3.

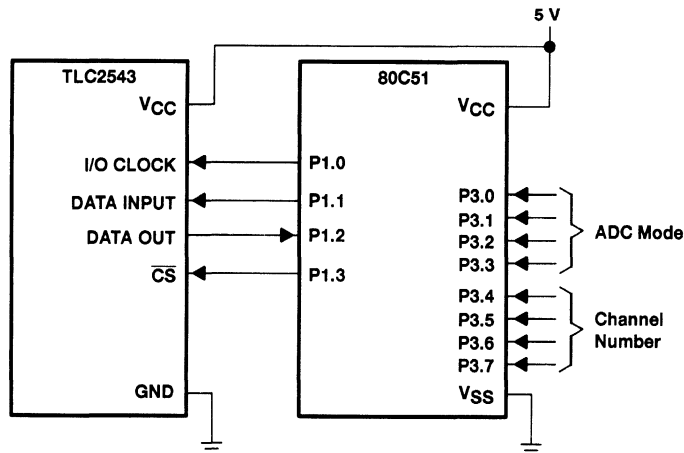


Figure 13. TLC2543 to 80C51 Microcontroller Interface

Software

The listing for the program used to control the interface circuit mentioned above is shown in List 4. As for the other microcontroller interface programs, it consists of a main program and two subroutines – TLC2543 and STORE.

The main program initializes the directions of the port 1 I/O terminals. P1.2 is configured as an input. P1.0, P1.1, and P1.3 are all programmed to perform as outputs. The chip select terminal of the TLC2543 is set high by setting P1.3. TLC2543 is then called. This subroutine contains the instructions which synthesize the SPI function and controls the exchange of data between the microcontroller and the TLC2543. The least significant bit first (LSBF) flag which is bit 1 of the channel select/mode data byte is checked to determine which byte (most significant – MSByte, least significant – LSByte) of the conversion result is to be expected first.

The SPI function is synthesized by using the accumulator in conjunction with the rotate left through carry (RLC) instruction to act as the SPI shift register. The following sequence provides a slow motion version of the SPI function.

The first bit of the first byte of the conversion result is read into the carry (C) bit. The contents of the accumulator are rotated left through carry and the first bit of the channel select/mode data is then output from P1.1. The first pulse of the serial clock is then provided by toggling the P1.0 bit of port 1 first high and then low. This sequence is repeated seven more times to complete the transfer of the first byte of data.

The second byte of data is transferred between the TLC2543 and the 80C51 by repeating the entire sequence of eight sets of data transfer and clock pulse. The MSByte is placed in register 2 (R2) and the LSByte is placed in register 3 (R3). The subroutine STORE is used to map the MSByte and LSByte conversion results into even and odd number RAM addresses corresponding to the particular channel number which has been selected.

List 4

LINE	LOC	OBJ	SOURCE
		1	; * * * * * * * * * * * * * * * * * *
		2	; * * * * * * * * * * * * * * * * * *
		3	; * TLC2543 12-bit Serial Out ADC to 80C51 * *
		4	; * * * * * * * * * * * * * * * * * *
		5	; * Microcontroller Interface Program * *
		6	; * * * * * * * * * * * * * * * * * *
		7	; * * * * * * * * * * * * * * * * * *
		8	; This program reads mode/channel select data into the
		9	; 80C51 via Port 4 and transmits this data to the
		10	; TLC2543 at the same time as reading the result from
		11	; the previous conversion and storing the result in an
		12	; adjacent pair of memory locations from 30H to 4CH.
		13	; MSByte - Even Address LSByte - Odd Address
		14	; MSByte Channel 0 in 30H, MSByte Channel 1 in 32H etc.
		15	;
0100		16	ORG 100H
0100	758150	17	START: MOV SP,#50H ;Initialise Stack Pointer
0103	759004	18	MOV P1,#04H ;Initialize port 1 I/O Pins
0106	C290	19	CLR P1.0 ;Set I/O clock low
0108	D293	20	SETB P1.3 ;Set chip select high
010A	74FF	21	MOV A,#00FFH
010C	3112	22	ACALL TLC2543
010E	313F	23	ACALL STORE
0110	80EE	24	JMP START
		25	
0112	ACB0	26	TLC2543:MOV R4,P3 ;Read mode/channel data into R4
0114	EC	27	MOV A,R4 ;and A
0115	C293	28	CLR P1.3 ;Set chip select low
0117	20E112	29	JB ACC.1,LSB ;If bit 1 of A is 1,
		30	;do LSByte first
011A	7D08	31	MSB: MOV R5,#08 ;Load MS bit counter
011C	A292	32	LOOP1: MOV C,P1.2 ;Read data bit into carry
011E	33	33	RLC A ;Rotate into accumulator
011F	9291	34	MOV P1.1,C ;Output mode/channel bit
0121	D290	35	SETB P1.0 ;Set I/O clock high
0123	C290	36	CLR P1.0 ;Set I/O clock low
0125	DDF5	37	DJNZ R5,LOOP1 ;Get/send another bit
0127	FA	38	MOV R2,A ;Put MSByte in R2
0128	EC	39	MOV A,R4 ;Put mode/channel data in A
0129	20E112	40	JB ACC.1,RETURN ;
012C	7D08	41	LSB: MOV R5,#08 ;Load LS bit counter
012E	A292	42	LOOP2: MOV C,P1.2 ;Read data bit into carry
0130	33	43	RLC A ;Rotate into accumulator
0131	9291	44	MOV P1.1,C ;Output mode/channel bit
0133	D290	45	SETB P1.0 ;Set I/O clock high
0135	C290	46	CLR P1.0 ;Set I/O clock low
0137	DDF5	47	DJNZ R5,LOOP2 ;Get/send another bit
0139	FB	48	MOV R3,A ;Put LSByte in R3
013A	EC	49	MOV A,R4 ;Put mode/channel data in A
013B	20E1DC	50	JB ACC.1,MSB ;If bit 1 of R4 is 1,
		51	;do MSbyte next
013E	22	52	RETURN: RET
		53	
013F	EC	54	STORE: MOV A,R4 ;Put mode/channel data in A
0140	54F0	55	ANL A,#0F0H ;Retain only channel number
0142	C4	56	SWAP A ;Swap high and low nibble of A
0143	75F002	57	MOV B,#02

List 4 (Continued)

LINE	LOC	OBJ	SOURCE
0146	A4	58	MUL AB
0147	2430	59	ADD A,#030H ;Add 30H to accumulator
0149	F9	60	MOV R1,A
014A	EA	61	MOV A,R2
014B	F7	62	MOV @R1,A ;Put MSByte in corresponding
		63	;even number address :-
		64	;Channel 0 in address 30H,
		65	;Channel 1 in address 32H etc.
014C	09	66	INC R1
014D	EB	67	MOV A,R3
014E	F7	68	MOV @R1,A ;Put LSByte in corresponding
		69	;odd number address :-
		70	;Channel 0 in address 31H,
		71	;Channel 1 in address 33H etc.
014F	22	72	RET
		73	END

Analog Considerations

Power Supply Decoupling

Care should be taken with the design of the printed circuit board when using 12-bit devices such as the TLC2543. The power supply terminal of each analog integrated circuit should be separately decoupled to the analog ground using a 0.1 μF ceramic capacitor. The inclusion of a 10 μF tantalum capacitor in parallel with the ceramic capacitor at each device supply terminal is also recommended, particularly in noisy environments.

Grounding

Separate ground return paths for analog and digital components back to the power supply should be used to prevent any noise currents induced by digital components from passing through the analog ground return path. These noise currents can induce noise voltages to occur in the analog ground return and thus corrupt the analog signal. Remember that, for a 5-V full scale signal, only 600 microvolts represents approximately half an LSB for a 12-bit ADC.

The important point to remember is that all ground return paths have a finite impedance. This impedance should be kept to a minimum by the use of wide printed circuit board tracks or ground planes where possible. A separate star connected ground topology is recommended for the analog components. This involves connecting each analog component's ground terminal to a central star point, which can then be connected via a wide printed circuit track to the power supply ground connection.

Board Layout

Digital devices and power switching elements should be kept as far away physically from analog components, such as the TLC2543, as possible. Particular attention should be paid to the use of switching power supplies. The high frequency switching currents which flow in the ground return paths of these space saving power blocks can introduce several LSBs of noise into 12-bit analog circuits. Linear regulated power supplies should be used or, if essential, switching regulators should be as far as possible from the analog circuitry with their outputs decouple.

Judicious use of ground planes can help to reduce analog ground impedances.

Figure 14 illustrates a typical bypassing scheme for the TLC2543-to-TMS370 microcontroller interface.

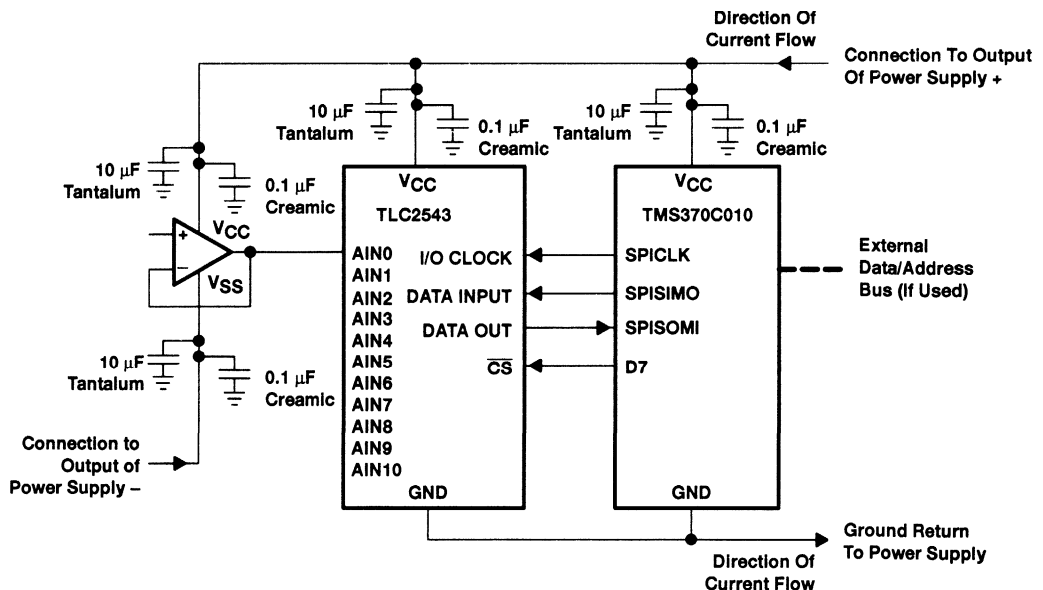


Figure 14. TLC2543 to Microcontroller Interface: Grounding and Decoupling Scheme

Appendix A

References

H8/325 Hardware User's Manual	Hitachi
H8/300 Series Programming Manual	Hitachi
Embedded Microcontrollers and Processors Vol 1	Intel Corporation
M68HC11 Reference Manual (1991)	Motorola Inc.
TMS370 Family Data Manual (1993)	Texas Instruments Incorporated
TLC2543 Data Sheet (Dec. '93)	Texas Instruments Incorporated

Acknowledgement

I wish to express my thanks to Mike Williams (Microcontroller Field Applications Engineer – Northern European Industrial Segment) for his useful comments on the TMS370 interface.

Interfacing the TLC32040 Family to the TMS320 Family

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1 Introduction

The TLC32040 and TLC32041 analog interface circuits are designed to provide a high level of system integration and performance. The analog interface circuits combine high resolution A/D and D/A converters, programmable filters, digital control and timing circuits as well as programmable input amplifiers and multiplexers. Emphasis is placed on making the interface to digital signal processors (the TMS320 family) and most microprocessors as simple as possible. This application report describes the software and circuits necessary to interface to numerous members of the TMS320 family. It presents three circuits for interfacing the TLC32040 Analog Interface Circuit to the TMS320 family of digital signal processors. Details of the hardware and software necessary for these interfaces are provided.

To facilitate the discussion of the software the following definitions and naming conventions are used:

1. >nnnn – a number represented in hexadecimal.
2. Interrupt service routine – a subroutine called in direct response to a processor interrupt.
3. Interrupt subroutine – any routine called by the interrupt service routine.
4. Application program (application routine) – the user's application dependent software (e.g., digital filtering routines, signal generation routines, etc.)

2 TLC32040 Interface to the TMS32010/E15

2.1 Hardware

Because the TLC32040 (Analog Interface Circuit) is a serial-I/O device, the interface to the TMS32010, which has no serial port, requires a small amount of glue-logic. The circuit shown in Figure 1 accomplishes the serial-to-parallel conversion for the AIC operating in synchronous mode.

2.1.1 Parts List

The interface circuit for the TMS32010 uses the following standard logic circuits:

1. One SN74LS138 3-to-8-line address decoder
2. One SN74LS02 Quad NOR-Gate
3. One SN74LS00 Quad NAND-Gate
4. One SN74LS04 Hex Inverter
5. One SN74LS74 Dual D-Flip-Flop
6. Two SN74LS299 8-bit Shift Registers

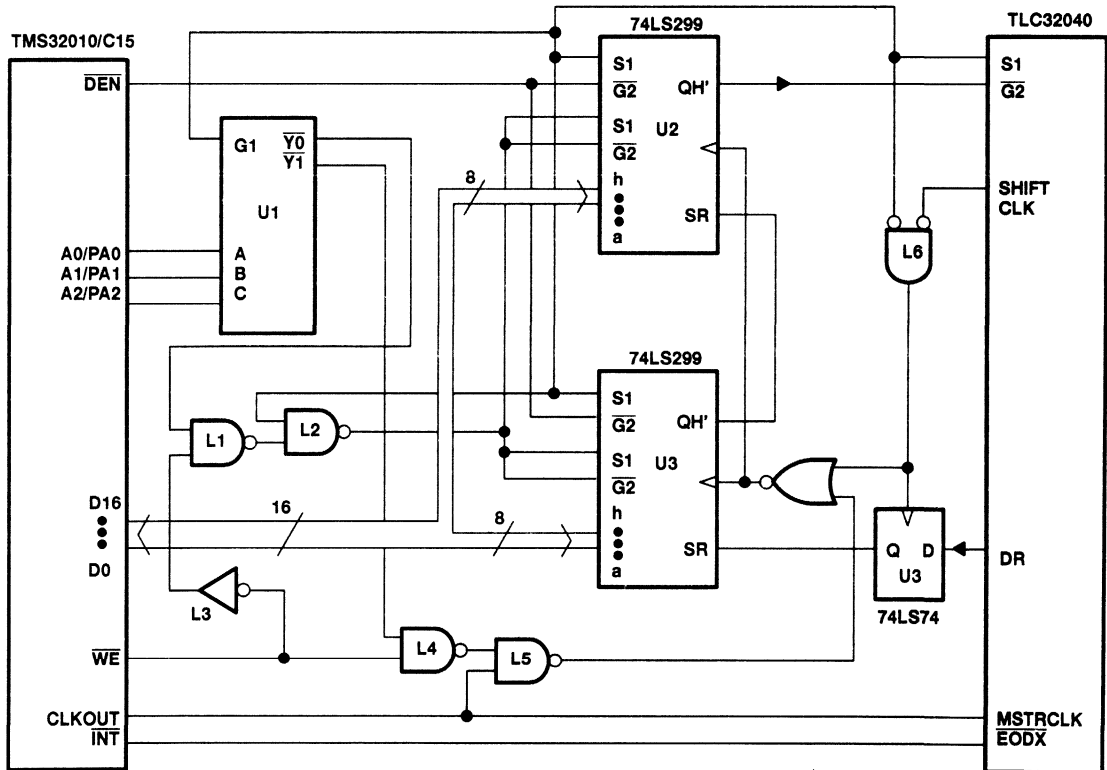


Figure 1. AIC Interface to TMS32010/E15

2.1.2 Hardware Description

The SN74LS138 is used to decode the addresses of the ports to which the TLC32040 and the interface logic have been mapped. If no other ports are needed in the development system, this device may be eliminated and the address lines of the TMS32010 used directly in place of $\overline{Y1}$ and $\overline{Y0}$ (see Figure 1).

Since the interface circuits are only addressed when the TMS32010 executes an IN or an OUT instruction, gates L1, L2, L3, L4, and L5 are required to enable reading and writing to the shift registers only on these instructions. The TBLW instruction is prohibited because it has the same timing as the OUT instruction. Flip-flop U4 ensures that the setup and hold times of SN74LS299 shift registers are met.

Although not shown in the circuit diagram, it is recommended that the \overline{CLR} pins of the SN74LS299 shift registers as well as the \overline{RESET} pin of the AIC be tied to the power-up reset circuit shown in the AIC data sheet. This ensures that the registers are clear when the AIC begins to transfer data and decrease the possibility that the AIC will shift in bad data which could cause the AIC to shut down or behave in an unexpected manner.

2.2 Software

The flowcharts for the communication program along with the TMS32010 program listing are presented in Appendix A. If this software is to be used, and application program that moves data into and out of the transmit and receive registers must be supplied.

2.2.1 Initializing the Digital Signal Processor

As shown in the flowcharts in Appendix A, the program begins with an initialization routine which clears both the transmit/receive-end flag and the secondary communication flag, and stores the addresses of the interrupt subroutines. The program uses the MPYK...PAC instruction sequence to load data memory locations with the 12-bit address of the subroutines. This sequence is only necessary if the subroutines are to reside in program memory locations larger than >00FF. Otherwise, the instructions LACK and SACL may be used to initialize the subroutine-address storage locations.

2.2.2 Communicating with the TLC32040

After the storage registers and status register have been initialized, the interrupt is enabled and control is passed to the user's application routine (i.e., the system-dependent software that processes received data and prepares data for transmission). The program ignores the first interrupt that occurs after interrupts are enabled (page 22, line 207, IGINT routine), allowing the AIC to stabilize after a reset. The application routine should not write to the shift registers while data is moving into (and out of) them. In addition, it should ensure that no primary data is written to the shift registers between a primary and secondary data-communication pair. The first objective can be accomplished by writing to the SN74LS299 shift registers as quickly as possible after the receive interrupt. The number of instruction cycles between the data transfers can be calculated from the conversion frequency. By counting instruction cycles in the application program, it is possible to determine whether the data transfer will conflict with the OUT instruction to the shift register. The second objective can be accomplished by monitoring SNDFLG in the application program. If SNDFLG is true (>00FF), secondary communication has not been completed.

When the processors receives an interrupt, the program counter is pushed onto the hardware stack and then the program counter is set to >0002, the location of the interrupt service routine, INTSVC (page 19, line 46). The interrupt service routine then saves the contents of the accumulator and the status register and calls the interrupt subroutine to which XVECT points. If secondary communication is to follow the upcoming primary communication, XVECT, is set by the application program to refer to SINT1, otherwise, XVECT defaults to NINT (i.e., the normal interrupt routine).

Because the interrupt subroutine makes one subroutine call and uses two levels of the hardware stack, the application program can only use two levels of nesting (i.e., if stack extension is not used). This means that any subroutine called by the application program can only call subroutines containing no instructions that use the hardware stack (e.g., TBLW) and that make no other subroutine calls. In addition, if the application program and communication program are being implemented on an XDS series emulator, the emulator consumes one level of the hardware stack and allows the application program only one level of nesting (i.e., one level of subroutine calls).

As shown in the flowcharts in Appendix A, the normal interrupt routine reads the A/D data from the shift registers and then sets the receive/transmit end-flag (RXEFLG). The application program must write the outgoing D/A data word to the shift registers at a time convenient to the application routine. It should have the restriction that the data be written before the next data transfer.

2.2.3 TLC32040 Secondary Communication

If it is necessary to write to the control register of the AIC or configure any of the AIC internal counters, the application program must initiate a primary/secondary communication pair. This can be accomplished by placing a data word in which bits 0 and 1 are both high into DXMT, placing the secondary control word (see program listing page 19) in D2ND, and placing the address of the secondary communication subroutine, SINT1, in XVECT. When the next interrupt occurs, the interrupt subroutine will call routine SINT1. SINT1 reads the A/D information from the shift registers and writes the secondary communication word to the shift registers.

3 TLC32040 Interface to the TMS32020/C25

3.1 Hardware Description

Because the TLC32040 is designed specifically to interface with the serial port of the TMS32020/C25, the interface requires no external hardware. Except for CLKR and CLKX, there is a one-to-one correspondence between the serial port control and data pins of TMS32020 and TLC32040. CLKR and CLKX are tied together since both the transmit and the receive operations are synchronized with SHIFT CLK of the TLC32040. The interface circuit, along with the communication program (page 26), allows the AIC to communicate with the TMS32020/C25 in both synchronous and asynchronous modes. See Figures 2, 3, and 4.

3.2 Software

The program listed in Appendix B allows the AIC to communicate with the TMS32020 in synchronous or asynchronous mode. Although originally written for the TMS32020, it will work just as well for the TMS320C25.

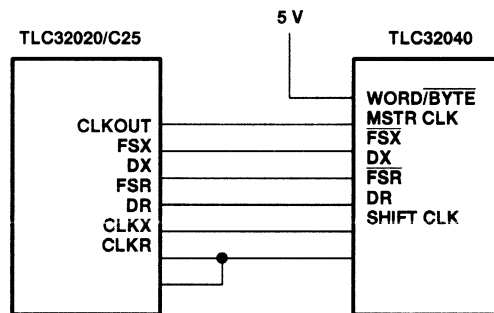
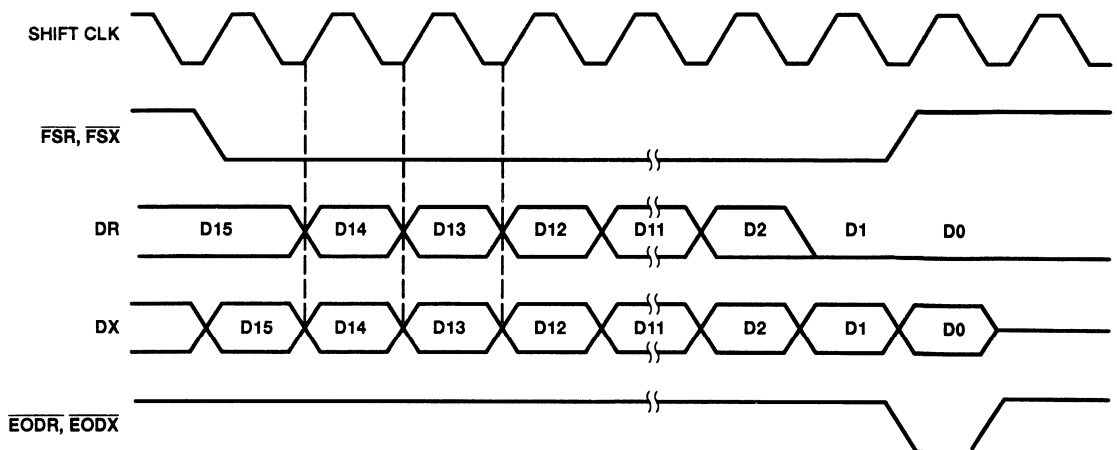


Figure 2. AIC Interface to TMS32020/C25



The sequence of operation is:

1. The FSX or FSR pin is brought low.
2. One 16-bit word is transmitted or one 16-bit byte is received.
3. The FSX or FSR pin is brought high.
4. The EODX or EODR pin emits a low-going pulse as shown.

Figure 3. Operating Sequence for AIC-TMC32020/C25 Interface

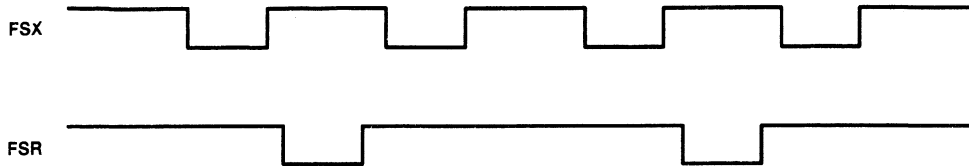


Figure 4. Asynchronous Communication AIC-TMS32020/C25 Interface

3.2.1 Initializing the TMS32020/C25

This program starts by calling the initialization routine. The working storage registers for the communication program and the transmit and receive registers of the DSP are cleared, and the status registers and interrupt mask register of the TMS32020/C25 are set (see program flow charts in Appendix B). The addresses of the transmit and receive interrupt subroutines are placed in their storage locations, and the addresses of the routines which ignore the first transmit and receive interrupts are placed in the transmit and receive subroutine pointers (XVECT and RVECT). The TMS32020/C25 serial port is configured to allow transmission of 16-bit data words (FO), the serial port format bit of the TMS32020/C25 must be set to zero) with an externally generated frame synchronization ($\overline{\text{FSX}}$ and $\overline{\text{FSR}}$ are inputs, TXM bit is set to 0).

3.2.2 Communicating with the TLC32040

After the TMS32020/C25 has been initialized, interrupts are enabled and the program calls subroutine IGR. The processor is instructed to wait for the first transmit and receive interrupts (XINT and RINT) and ignore them. After the TMS32020 has received both a receive and a transmit interrupt, the IGR routine will transfer control back to the main program and IGR will not be called again.

If the transmit interrupt is enabled, the processor branches to location 28 in program memory at the end of a serial transmission. This is the location of the transmit interrupt service routine. The program context is saved by storing the status registers and the contents of the accumulator. Then the interrupt service routine calls the interrupt subroutine whose address is stored in the transmit interrupt pointer (XVECT).

A similar procedure occurs on completion of a serial receive. If the receive interrupt is enabled, the processor branches to location 26 in program memory. As with the transmit interrupt service routine (XINT, page 30, line 226), the receive interrupt service routine (page 30, line 194) saves context and then calls the interrupt subroutine whose address is stored in the receive interrupt pointer (RVECT). It is important that during the execution of either the receive or transmit interrupt service routines, all interrupts are disabled and must be re-enabled when the interrupt service routine ends.

The main program is the application program. Procedures such as digital filtering, tone-generation and detection, and secondary communication judgment can be placed in the application program. In the program listing shown in Appendix B, a subroutine (C2ND) is provided which will prepare for secondary communication. If secondary communication is required, the user must first write the data with the secondary code to the DXMT register. This data word should have the two least significant bits set high (e.g., >0003). The first 14 bits transmitted will go to the D/A converter and the last two bits indicate to the AIC that secondary communication will follow. After writing to the SXMT register, the secondary communication word should be written to the D2ND register.

This data may be used to program the AIC internal counters or to reconfigure the AIC (e.g., to change from synchronous to asynchronous mode or to bypass the bandpass filter). After both data words are stored in their respective registers, the application program can then call the subroutine C2ND which will prepare the TMS32020 to transmit the secondary communication word immediately after primary communication.

3.2.3 Secondary Communicating – Special Considerations

This communication program disables the receive interrupt (RINT) when secondary communication is requested. Because of the critical timing between the primary and secondary communication words and because RINT carries a higher priority than the transmit interrupt, the receive interrupt cannot be allowed to interrupt the processor before the secondary data word can be written to the data-transmit register. If this situation were to occur, the AIC would not receive the correct secondary control word and the AIC could be shut down.

In many applications, the AIC internal registers need only be set at the beginning of operation, (i.e., just after initialization). Thereafter, the DSP only communicates with the AIC using primary communication. In cases such as these, the communication program can be greatly simplified.

4 TMS32040 Interface to the TMS320C17

4.1 Hardware Description

As shown in Figure 5, the TMS320C17 interfaces directly with the TLC32040. However, because the TMS320C17 responds more slowly to interrupts than the TMS32010/E15 or the TMS32020/C25, additional circuit connections are necessary to ensure that the TMS320C17 can respond to the interrupt, accomplish the context-switching that is required when an interrupt is serviced, and proceed with the interrupt vector. This must all be accomplished within the strict timing requirements imposed by the TLC32040. To meet these requirements, $\overline{\text{FSX}}$ of the TLC32040 is connected to the $\overline{\text{EXINT}}$ pin of the TMS320C17. This allows the TMS320C17 to recognize the transmit interrupt before the transmission is complete. This allows the interrupt service routine to complete its context-switching while the data is being transferred. The interrupt service routine branches to the interrupt subroutines only after the FSX flag bit has been set. This signals the end of data transmission.

The other hardware modification involves connecting the $\overline{\text{EODX}}$ pin of the TLC32040 to the $\overline{\text{BIO}}$ pin of the TMS320C17. Because the TMS320C17 serial port accepts data in 8-bit bytes (see Figure 6) and the TLC32040 controls the byte sequence (i.e., which byte is transmitted first, the high-order byte or the low-order byte) it is important that the TMS320C17 be able to distinguish between the two transmitted bytes. The $\overline{\text{EODX}}$ signal is asserted only once during each transmission pair, making it useful for marking the end of a transmission pair and synchronizing the TMS320C17 with the AIC byte sequence. After synchronization has been established, the $\overline{\text{BIO}}$ line is no longer needed by the interface program and may be used elsewhere.

Because the TMS320C17 serial port operates only in byte mode, 16-bit transmit data should be separated into two 8-bit bytes and stored in separate registers before a transmit interrupt is acknowledged. Alternatively, the data can be prepared inside the interrupt service routine before the interrupt subroutine is called. From the time that the interrupt is recognized to the end of the data transmission is equivalent to 28 TMS320C17 instruction cycles.

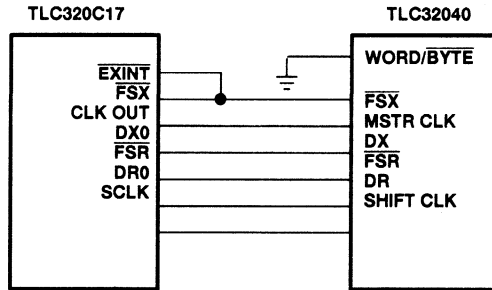
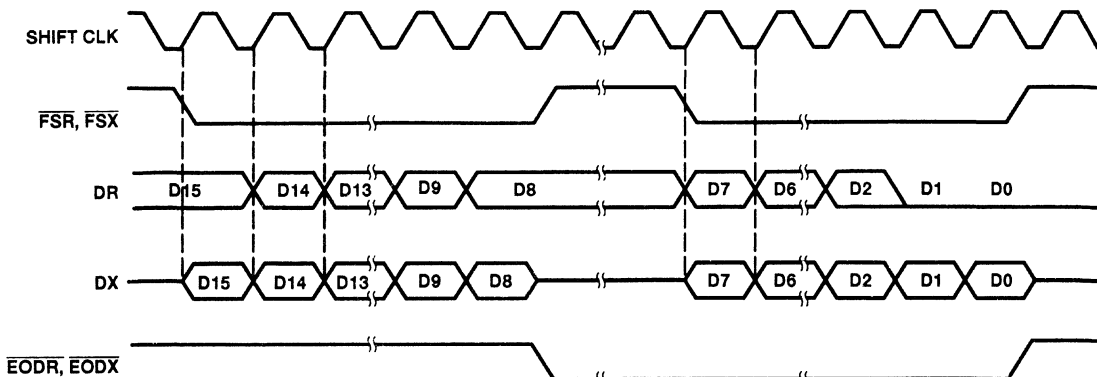


Figure 5. AIC Interface to TMS320C17



The sequence of operation is:

1. The FSX or FSR pin is brought low.
2. One 8-bit word is transmitted or one 8-bit byte is received.
3. The EODX or EODR pins are brought low.
4. The FSX or FSR emit a positive frame-sync pulse that is four shift clock cycles wide.
5. One 8-bit byte is transmitted and one 8-bit byte is received.
6. The EODX and EODR pins are brought high.
7. The FSX and FSR pins are brought high.

Figure 6. Operating Sequence for AIC-TMS320C17

4.2 Software

The software listed in Appendix C only allows the AIC to communicate with the TMS320C17 in synchronous mode. This communication program is supplied with an application routine, DLB (Appendix C, program listing line 253), which returns the most recently received data word back to the AIC (digital loopback).

4.2.1 Initializing the TMS320C17

The program begins with an initialization routine (INIT, page 40, line 120). Interrupts are disabled and all the working storage registers used by the communication program are cleared. Both transmit registers are cleared, the constants used by the program are initialized and the addresses of the subroutines called by the program are placed in data memory. This enables the interrupt service routine to call subroutines located in program-memory addresses higher than 255. After the initialization is complete, the TMS320C17 monitors the FSX interrupt flag in the control register to establish synchronization with the AIC.

4.2.2 AIC Communications and Interrupt Management

Because the AIC FSX pin is tied to the $\overline{\text{EXINT}}$ line of the TMS320C17 and the delay through the interrupt multiplexer, the interrupt service routine is called four instruction cycles after the falling edge of FSX. The interrupt service routine (INTSVC, Appendix C, program listing, line 90) completes its context switching and then monitors the lower control register, polling the FSX flag bit that indicates the end of the 8-bit serial data transfer. If the FSX flag bit is set, the transfer is complete. After this bit is set, control is transferred to the interrupt subroutine whose address is stored in VECT. The serial communication must be complete before data is read from the data receive register.

When no secondary communication is to follow, the interrupt subroutines, NINT1 and NINT2, are called. If data has been stored in DXMT2 (the low-order eight bits of the transmit data word), which does not indicate that secondary communication is to follow, the interrupt service routine calls NINT1 when the first 8-bit serial transfer is complete. NINT1 immediately writes the second byte of transmit data, (i.e., the contents of DXMT2) to transmit data register 0 (TRO). It then moves the first byte of the received data (i.e., the high-order byte of the A/D conversion result) into DRCV1. NINT1 then stores in VECT the address of NINT2. NINT2 is called at the end of the next 8-bit data transfer and resets the $\overline{\text{FSX}}$ interrupt flag bit by writing a logic high to it. The next interrupt (a falling edge of $\overline{\text{EXINT}}$) occurs before the interrupt service routine returns control to the main

program. This is an acceptable situation since the TMS320C17, on leaving the interrupt service routine, recognizes that an interrupt has occurred and immediately responds by servicing the interrupt.

The interrupt subroutine NINT2 is similar in operation to NINT1. It stores the low-order byte of receive data (bits 7 through 0 of the A/D conversion result) and stores the address of the next interrupt subroutine in VECT. NINT2 does not write to the transmit data register, TR0. This task has been left to the application program. After the transmit data has been prepared by the main program and the data has been stored in DXMT1 and DXMT2, the main program stores the first byte of the transmit data in transmit data register 0 (TR0).

4.2.3 Secondary Communications

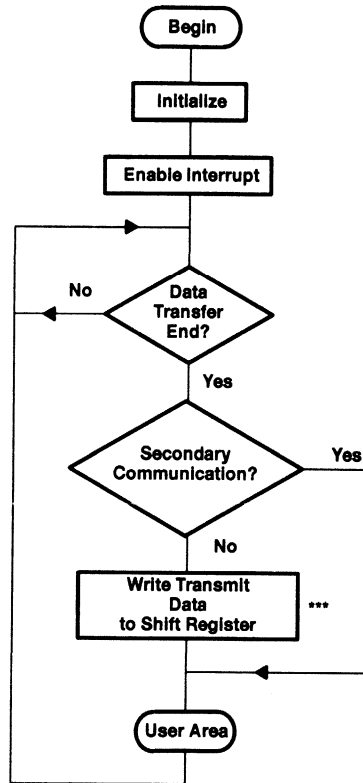
The interrupt subroutines SINT1 through SINT4 are called when secondary communication is required. For secondary communication, DXMT1 and DXMT2 will hold the primary communication word. DXMT3 and DXMT4 will hold the secondary communication word. VECT, the subroutine pointer should then be initialized to the address of SINT1. As with the normal (primary communication only) interrupt subroutines (i.e., NINT1 and NINT2), the secondary communication routines will change VECT to point to the succeeding routine (e.g., SINT1 will point to SINT2, SINT2 will point to SINT3, etc.).

5 Summary

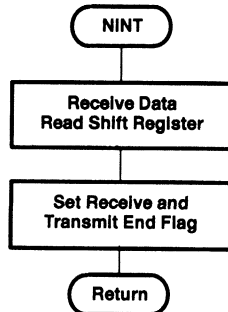
The TLC32040 is an excellent choice for many digital signal processing applications such as speech recognition/storage systems and industrial process control. The different serial modes of the AIC (synchronous, asynchronous, 8- and 16-bit) allow it to interface easily with all of the serial port members of the TMS320 family as well as other processors.

A TLC32040 and TMS32010 Flowcharts and Communication Program

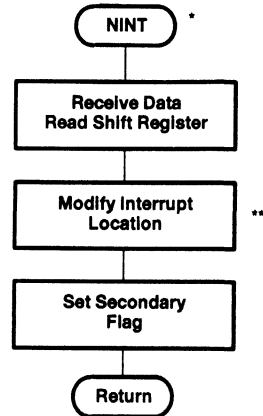
A.1 Flowcharts



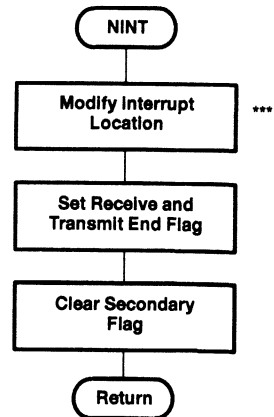
a. MAIN



b. PRIMARY INTERRUPT ROUTINE



c. SECONDARY DATA COMMUNICATIONS 1



d. SECONDARY DATA COMMUNICATIONS 2

- * Set, if need secondary.
- ** Modify to call SINT2.
- *** Modify to call NINT.
- **** Must execute before transfer beginning.

A.2 Communication Program List

```

0001      *****
0002      * When using this program, the circuit in the TLC32040 *
0003      * data sheet or its equivalent circuit must be fused *
0004      * port 1 are reserved for data receiving and data *
0005      * transmitting. The TBLW command is prohibited because *
0006      * it has the same timing as the OUT command. TLC32040 is *
0007      * used only in synchronous mode. *
0008      *****
0009      *
0010      0002 RXEFLG EQU >02 receive and xmit end flag.
0011      0003 SNDFLG EQU >03 secondary communication flag.
0012      0004 DRCV EQU >04 receive data storage.
0013      0005 DXMT EQU >05 xmit data storage.
0014      0006 D2ND EQU >06 secondary data storage.
0015      0007 XVECT EQU >07 interrupt address storage.
0016      0008 ACHSTK EQU >08 ACCH stack.
0017      0009 ACLSTK EQU >09 ACCL stack.
0018      000A SSTSTK EQU >0A Status stack.
0019      000C ANINT EQU >0C interrupt address 1
0020      000D ASINT1 EQU >0D interrupt address 2
0021      000E ASINT2 EQU >0E interrupt address 3
0022      000F TMP0 EQU 0F temporary register.
0023      *
0024      00FF SET EQU >FF
0025      0001 ONE EQU >01
0026      * =====
0027      * Reset vector.
0028      * =====
0029 0000 AORG >0000 program start address.
0030 0000 F900 B EPIL jump to initialization.
0001 000D

0031      *****
0032      * ===== *
0033      * Interrupt vector. *
0034      * ===== *
0035      * When secondary communication, modify the content of *
0036      * XVECT to the address of secondary communication and *
0037      * store secondary data in D2ND. *
0038      * ex. *
0039      * LAC ASINT1,0 modify XVECT *
0040      * SACL XVECT,0 *
0041      * | *
0042      * LAC D2ND,0 store secondary data. *
0043      *****

```

```

0044 0002                AORG >0002    interrupt vector.
0045 0002
0046 0002  7C0A  INTSVC  SST  SSTSTK  push status register.
0047 0003  6E01                LDPK  ONE    set data pointer one.
0048 0004  5808                SACH  ACHSTK push ACCH.
0049 0005  5009                SACL  ACLSTK push ACCL.
0050 0006  2007                LAC   XVECT,0 load interrupt address.
0051 0007  7F8C                CALA                branch to interrupt routine.
0052 0008  6508                ZALH  ACHSTK  pop ACCH
0053 0009  7A09                OR    ACLSTK  pop ACCL.
0054 000A  7B0A                LST   SSTSTK  pop stack register.
0055 000B  7F82                EINT                enable interrupt.
0056 000C  7F8D                RET                return from interrupt routine.
0057                *****
0058                *          -----          *
0059                *      Initialization after reset.      *
0060                *          -----          *
0061                *
0062                *      Data RAM locations 82H(130) through 8FH(143),
0063                *      12 words of page 1, are reserved for this
0064                *      program. The user must set the status register
0065                *      by adding the SST command at the end of the
0066                *      the initialization routine.
0067                *****
0068                *
0069                *
0070                *
0071 000D                AORG $          initial program.
0072 000D
0073 000D  6E01  EPIL    LDPK  ONE    set data page pointer one.
0074 000E
0075 000E  7E01                LACK  ONE    save normal communication
0076 000F  500F                SACL  TMP0   address to its storage.
0077 0010  6A0F                LT    TMP0
0078 0011  802C                MPYK  NINT
0079 0012  7F8E                PAC
0080 0013  500C                SACL  ANINT
0081 0014
0082 0014  8030                MPYK  SINT1  save secondary communication
0083 0015  7F8E                PAC        address1 to its storage.
0084 0016  500D                SACL  ASINT1
0085 0017
0086 0017  8037                MPYK  SINT2  save secondary communication
0087 0018  7F8E                PAC        address2 to its storage.
0088 0019  500E                SACL  ASINT2
0089 001A
0090 001A  803A                MPYK  IGINT  ignore interrupt once after
0091 001B  7F8E                PAC        master reset.
0092 001C  5007                SACL  XVECT
0093 001D
0094 001D  7F89                ZAC                clear flags.
0095 001E  5002                SACL  RXFLG,0
0096 001F
0097 001F  5003                SACL  SNDFLG,0

```

```

0098 0020
0099 0020
0100 0020
0101 0020 7F82          EINT          enable interrupt.
0102          *
0103          *****
0104          *          =====          *
0105          *          Main program.          *
0106          *          =====          *
0107          *
0108          * This program allows the user two levels of nesting *
0109          * since one level is used as stack for the interrupt. *
0110          * When the RXEFLG flag is false then no data transfer *
0111          * has occurred, if it is true then data transfer has *
0112          * finished. User routines such as digital filter, *
0113          * secondary-data-communication judgement etc., must be *
0114          * placed in this location. Depending on the sampling *
0115          * rate (conversion rate), these user routines must *
0116          * write the xmit data to the shift registers within *
0117          * approximately 500 instruction cycles. If the user *
0118          * requires secondary communication, it will be *
0119          * necessary to delay the OUT instruction until the *
0120          * secondary data transfer has finished.          *
0121 0021          *****
0122 0021 2002 MAIN LAC  RXEFLG,0 wait for interrupt.
0123 0022 FF00          BZ  MAIN
0124 0023 0021
0124 0024
0125 0024 2003          LAC  SNDFLG,0 skip OUT instruction during
0126 0025 FE00          BNZ  MAIN1 secondary communication.
0127 0026 0028
0127 0027
0128 0027 4905          OUT  DXMT,PA1 write xmit data to shift register.
0129 0028
0130 0028 7F89 MAIN1 ZAC          clear flags.
0131 0029 5002          SACL RXEFLG
0132 002A
0133 002A F900          B    MAIN  loop.
0134 002B 0021
0134
0135          *
0136          *****
0137          *          =====          *
0138          *          Normal interrupt routine.          *
0139          *          =====          *
0140          *          destroy ACC, DP.          *
0141          *
0141          * Write the contents of DXMT to the 'LS299s, receive *
0142          * DAC data in DRCV, and set RXEFLG flag.          *
0143          *****
0144 002C
0145 002C 4004 NINT IN  DRCV,PA0 receive data from shift register.
0146 002D

```



```

0147 002D 7EFF      LACK SET      set receive and xmit ended flag.
0148 002E 5002      SACL RXEFLG
0149 002F
0150 002F 7F8D      RET          return.
0151      *
0152      *****
0153      *      ===== *
0154      *      Secondary communication interrupt routine 1. *
0155      *      ===== *
0156      *      destroy ACC,DP *
0157      * *
0158      * Write the contents of D2ND to the 'LS299s, receive *
0159      * data in DRCV, and modify XVECT for secondary *
0160      * communication interrupt. *
0161      *****
0162 0030
0163 0030 4004 SINT1 IN      DRCV,PA0 receive data from shift register.
0164 0031
0165 0031 4906      OUT      D2ND,PA1 write secondary data to shift
0166      *      register.
0167 0032 200E      LAC      ASINT2,0 modify interrupt location.
0168 0033 5007      SACL XVECT secondary communication 2
0169 0034
0170 0034 7EFF      LACK SET      set secondary communication flag.
0171 0035 5003      SACL SNDFLG,0
0172 0036
0173 0036 7F8D      RET          return.
0174 0037
0175      *****
0176      *      ===== *
0177      *      Secondary communication interrupt routine 2. *
0178      *      ===== *
0179      *      destroy ACC,DP *
0180      * *
0181      * Modify XVECT for normal communication, and set *
0182      * RXEFLG flag. *
0183      *****
0184 0037
0185 0037 200C SINT2 LAC      ANINT      modify interrupt location
0186 0038 5007      SACL XVECT      normal communication.
0187 0039
0188 0039 7EFF      LACK SET      set receive and xmit ended flag.
0189 003A SACL RXEFLG
0190 003B
0191 003B 7F89      ZAC          clear secondary communication flag.
0192 003C 5003      SACL SNDFLG,0
0193 003D
0194 003D 7F8D      RET          return.
0195 003E

```

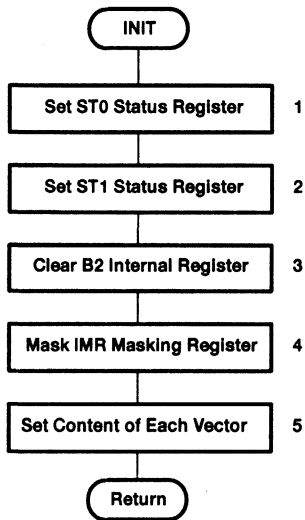
```

0196          *****
0197          *          =====          *
0198          *      Ignoring the first interrupt after reset.      *
0199          *          =====          *
0200          *                      destroy ACC,DP.                      *
0201          *
0202          *      Ignore the first interrupt after reset. the TLC32040 *
0203          *      receives zero as DAC data but no ADC data in DRCV.  *
0204          *
0205          *****
0206 003E
0207 003E 200C IGINT LAC  ANINT      modify interrupt location
0208 003F 5007          SACL  XVECT      normal communication.
0209 0040
0210 0040 7F8D          RET          return.
0211 0041
0212          END
NO ERRORS, NO WARNINGS

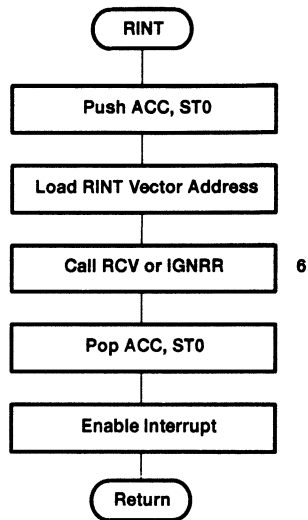
```

B TLC32040 and TMS32020 Flowcharts and Communication Program

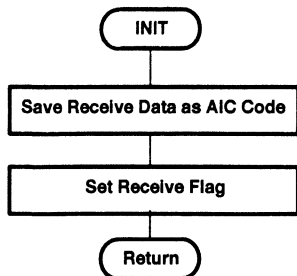
B.1 Flowcharts



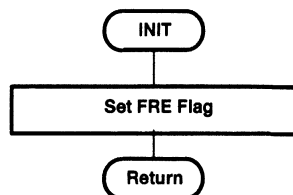
a. INITIALIZATION



b. RECEIVED INTERRUPT SERVICE ROUTINE

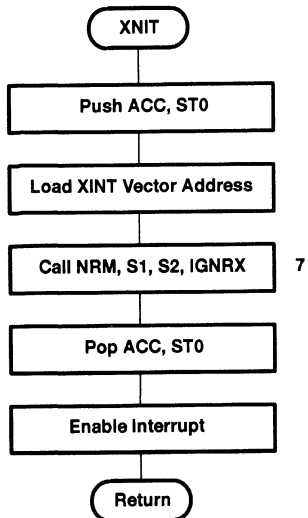


c. RECEIVE SUBROUTINE

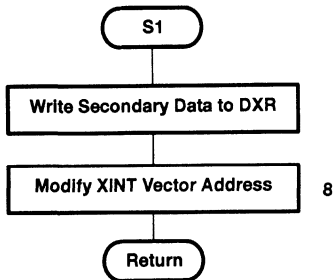


d. IGNORE INTERRUPT

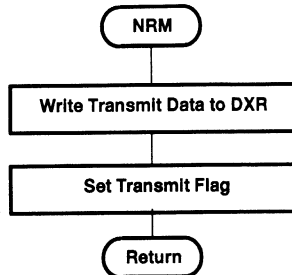
- 1 – Alterable AR pointer and OVM.
- 2 – Alterable CNF, SXM and XF.
- 3 – Must clear at least 108 through 127, 19 of internal RAM.
- 4 – If IMR is changed by user program. INST must be changed.
- 5 – Their contents will be changed by their routine locations.
- 6 – IGNRR is executed only once after reset.



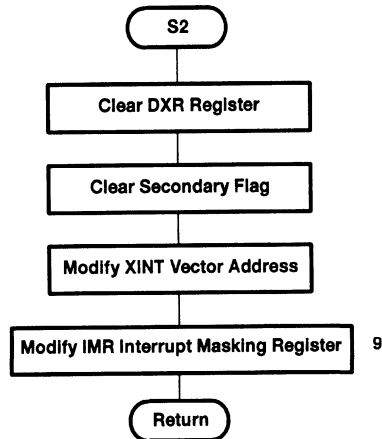
e. TRANSMIT INTERRUPT SERVICE ROUTINE



g. PRIMARY-SECONDARY COMMUNICATIONS 1



f. PRIMARY TRANSMISSION ROUTINE

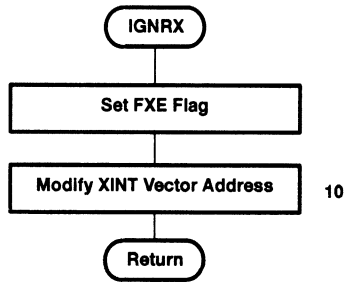


h. PRIMARY-SECONDARY COMMUNICATIONS 2

7 – IGNRX is executed only once after reset.

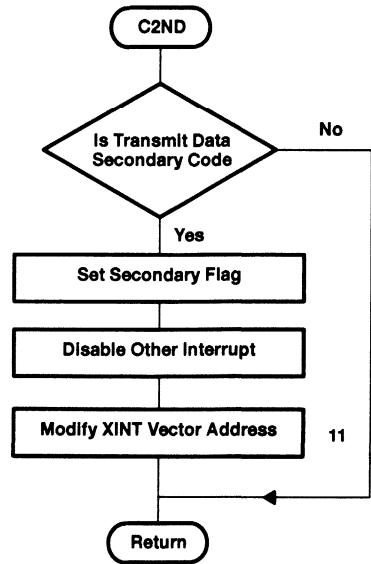
8 – Modify to S2 address.

9 – Modify to NRM address.

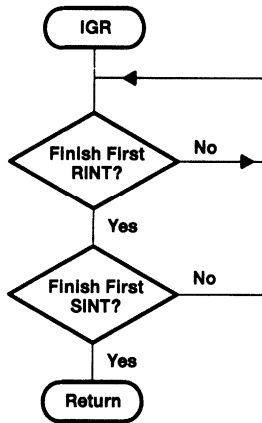


I. IGNORE TRANSMIT INTERRUPT

10 – Modify to NRM address.
 11 – Modify to S1 address.



J. SECONDARY COMMUNICATION JUDGEMENT



K. IGNORE FIRST INTERRUPTS

B.2 Communication Program List

```

0001 *****
0002 * =====
0003 * TLC32040 & TMS32020 communication program. *
0004 * =====
0005 * by H.Okubo & W.Rowand *
0006 * version 1.1 7/22/88. *
0007 * *
0008 * This is a TMS32020 - TLC32040 communication program *
0009 * that can be used in many systems. To use this program *
0010 * the TMS32020 and the TLC32040 (AIC) must be connected *
0011 * as shown in the publication: Linear and Interface *
0012 * Circuit Applications, Volume 3. The program reserves *
0013 * TMS32020 internal data memory 108 through 127 (B2) as *
0014 * flags and storage. When secondary communication is *
0015 * needed, every maskable interrupt except XINT is *
0016 * disabled until that communication finishes. *
0017 * *
0018 * If you have any questions, please let us know. *
0019 *****
0020 *
0021 *
0022 * =====
0023 * Memory mapped register.
0024 * =====
0025 *
0026 0000 DRR EQU * data receive register address.
0027 0001 DXR EQU 1 * data xmit register address.
0028 0004 IMR EQU 4 * interrupt mask register address.
0029 *
0030 * =====
0031 * Reserved onchip RAM as flags and storages.
0032 * (block B2 108 through 127.)
0033 * =====
0034 *
0035 006C FXE EQU 108 * ignore first XINT flag.
0036 006D FRE EQU 109 * ignore first RINT flag.
0037 006F TMPO EQU 111 * temporary register.
0038 0070 ACCHST EQU 12 * stack for ACCH.
0039 0071 CCLST EQU 113 * stack for ACCL.
0040 0072 SSTST EQU 114 * stack for STO register.
0041 0073 INTST EQU 115 * stack for IMR register.
0042 0074 RVECT EQU 116 * vector for RINT.
0043 0075 XVECT EQU 117 * vector for XINT.
0044 0076 VRCV EQU 118 * RINT vector storage.
0045 0077 VNRM EQU 119 * XINT vector storage.
0046 0078 VS1 EQU 120 * secondary vector storage1.
0047 0079 VS2 EQU 121 * secondary vector storage2.
0048 007A DRCV EQU 122 * receive data storage.
0049 007B DXMT EQU 123 * xmit data storage.
0050 007C D2ND EQU 124 * secondary data storage.
0051 007D FRCV EQU 125 * receive flag.
0052 007E FXMT EQU 126 * xmit flag.
0053 007F F2ND EQU 127 * secondary communication flag.
0054 *

```

```

0055      *****
0056      * Processor starts at this address after reset.      *
0057      *
0058 0000      AORG      0      * program start address.      *
0059 0000  FF80      B      STRT  * jump to initialization routine. *
0060 0001  0020
0060      *****
0061      *
0062      *****
0063      * Receive interrupt location.      *
0064      *
0065 001A      AORG      26     * Rint vector.      *
0066 001A  FF80      B      RINT  * jump to receive interrupt      *
0067 001B  004A      * routine.      *
0068      *****
0069      *
0070      * Transmit interrupt location.      *
0071      *
0072 001C      AORG      28     * Xint vector.      *
0073 001C  FF80      B      XINT  * jump to xmit interrupt routine. *
0074 001D  005A
0074      *****
0075      *
0076 0020      AORG      32     * start initial program.
0077      *
0078      *****
0079      * User must initialize DSP with the routine INIT.      *
0080      * The user may modify this routine to suit his      *
0081      * requirements as he likes.      *
0082      *****
0083 0020  FE80  STRT  CALL  INIT  *
0084 0021  0025
0084 0022  CE00      EINT      * enable interrupt.
0085 0023  FE80      CALL  IGR
0086 0024  008D
0086      *

```

```

0087 *****
0088 *                               ===== *
0089 *                               User area *
0090 *                               ===== *
0091 *                               *
0092 * This program allows the user two levels of nesting, *
0093 * since two levels are used as stack for the interrupt. *
0094 * When the FXMT flag is false no data has occurred *
0095 * When the FRCV flag is false, no data has been *
0096 * received. As those flags are not reset by any *
0097 * routine in this program, the user must reset the *
0098 * flags if he chooses to use them and note that >00ff *
0099 * means true, >0000 means false. User routines such as *
0100 * digital filtering, FFTs etc. must be placed in this *
0101 * location. Depending on the sampling rate (conver- *
0102 * sion rate), these user routines must write the xmit *
0103 * data to the DXMT registers within approximately 500 *
0104 * instruction cycles. If the user requires secondary *
0105 * communication, data with the secondary code (xxx *
0106 * xxxx xxxx xx11) should first be written to DXMT and *
0107 * then secondary data should be written to D2ND. Next, *
0108 * a call should be made to C2ND to set up SVECT and the *
0109 * F2ND flag to perform the secondary communication. *
0110 * Note that all maskable interrupts except XINT are *
0111 * disabled until secondary communication has completed. *
0112 *****
0113 *
0114 *****
0115 *                               ===== *
0116 *                               Initialization routine. *
0117 *                               ===== *
0118 * This routine initializes the status registers, flags, *
0119 * vector storage contents and internal data locations *
0120 * 96 through 107. Note that the user can modify these *
0121 * registers (i.e., STO ST1 IMR), as long as the contents *
0122 * do not conflict with the operation of the AIC. *
0123 *****
0124 0025 C800 INIT LDPK 0 * set status0 register.
0125 0026 D00I LALK >OE00,0 * 0000 1110 0000 D000B
0126 0027 OE00
0126 0028 606F SACL TMPO,0 * ARP=0 AR pointer 0
0127 0029 506F LST TMPO * OV =0 (Overflow reg-clear)
0128 * * OVM=1 (Overflow mode set to 1)
0129 * * ? =1 Not affected.
0130 * * INTM=1 Not affected
0131 * * DP 000000000 page 0
0132 *
0133 * * set status1 register.
0134 *
0135 002A D00I LALK >03F0 * 0000 0011 1111 0000B
0136 002B 03F0
0136 002C 606F SACL TMPO,0 * APB=0
0137 002D 516F LST1 TMPO * CNF=0 (Set B0 data memory)
0138 002E

```



```

0139      *
0140      *
0141      *
0142      *
0143      *
0144      *
0145      *
0146      *
0147      *
0148 002E CA00      ZAC      * clear registers
0149 002F 6001      SACL DXR,0  *
0150 0030 6000      SACL DRR,0  *
0151 0031 C060      LARK AR0,96 * clear Block B2.
0152 0032 CBIF      RPTK 31    *
0153 0033 60A0      SACL +,0   *
0154      *
0155      * Interrupt masking
0156      *
0157 0034 CA30      LACK >30   * 0000 0000 0011 0000B
0158 0035 6004      SACL IMR,0  * INT _____|| ||||
0159 0036 6073      SACL INTST,0 * RINT_____|| ||||
0160      *
0161      *
0162      *
0163      *
0164      *
0165 0037 D001      LALK NRM,0  * normal xint routine address.
      0038 0067
0166 0039 6077      SACL VNRM,0 *
0167
0168 003A D001      LALK S1,0   * secondary xint routine address 1.
      003B 006C
0169 003C 6078      SACL VS1,0  *
0170      *
0171 003D D001      LALK S2,0   * secondary xint routine address 2.
      003E 0071
0172 003F 6079      SACL VS2,0  *
0173      *
0174 0040 D001      LALK RCV,0  * rint routine address.
      0041 0055
0175 0042 6076      SACL VRCV,0
0176      *
0177 0043 D001      LALK IGNRR,0 * set ignore first rint address.
      0044 0094
0178 0045 6074      SACL RVECT,0
0179      *
0180 0046 D001      LALK IGNRX,0 * set ignore first xint address.
      0047 0099
0181 0048 6075      SACL XVECT,0
0182 0049 CE26      RET      * return.
0183 004A

```

```

0184      *
0185      *****
0186      *           ===== *
0187      *           Receive interrupt routine. *
0188      *           ===== *
0189      * This routine stores receive data in its storage DRCV *
0190      * (112 page0) and sets the receive flag FRCV (125 page0)*
0191      * As two levels of nesting are used, this routine *
0192      * allows the user two levels, without stack extension . *
0193      *****
0194 004A 7872 RINT SST SSTST * push STO register.
0195 004B C800 LDPK 0 * data pointer page 0.
0196 004C 6071 SACL ACCLST,0 * push ACCL.
0197 004D 6870 SACH ACCHST,0 * push ACCH.
0198 004E 2074 LAC RVECT,0 * load ACC vector address.
0199 004F CE24 CALA
0200 0050 4171 ZALS ACCLST * pop ACC
0201 0051 4870 ADDH ACCHST
0202 0052 5072 LST SSTST * pop ST register.
0203 0053 CE00 EINT * enable interrupts.
0204 0054 CE26 RET * return.
0205      *
0206 0055 2000 RCV LAC DRR,0 * load data from DRR.
0207 0056 607A SACL DRCV,0 * save it to its storage.
0208 0057 CAFF LACK >FF * set receive flag.
0209 0058 607D SACL FRCV *
0210 0059 CE26 RET * return.
0211      *
0212      *****
0213      *           ===== *
0214      *           xmit interrupt routine. *
0215      *           ===== *
0216      * This routine writes xmit data C%the contents of DXMT *
0217      * (123 page0)) to the DXR register according to the type*
0218      * of communication, i.e. normal communication or secondary *
0219      * communication. For normal communication, call the normal *
0220      * communication routine (NRM). For secondary, call the *
0221      * secondary communication routines (S1 and S2). Because *
0222      * these routines use two levels of nesting, the user is *
0223      * allowed two levels of nesting if stack extension is *
0224      * not used. *
0225      *****
0226 005A 7872 XINT SST SSTST * push ST register.
0227 005B C800 LDPK 0 * data pointer page 0.
0228 005C 6071 SACL ACCLST,0 * push ACCL.
0229 005D 6870 SACH ACCHST,0 * push ACCH.
0230 005E 207C LAC D2ND,0 * preload dxr with secondary
0231 005F 6001 SACL DXR,0 * communication data.
0232 0060 2075 LAC XVECT,0 * load vector address.
0233 0061 CE24 CALA * call xmit routine.
0234 0062 4171 ZALS ACCLST * POP ACC
0235 0063 4870 ADDH ACCHST
0236 0064 5072 LST SSTST * pop ST register.
0237 0065 CE00 EINT * enable interrupt.
0238 0066 CE26 RET * return.

```

```

0239 *****
0240 *          ===== *
0241 *          Normal data write routine. *
0242 *          ===== *
0243 * This routine is called when normal communication occurs.*
0244 * This routine writes xmit data to DXR, and sets the *
0245 * transmit flag (126 page0). *
0246 *****
0247 *
0248 0067 207B NRM      LAC DXMT,0      * write DXR data.
0249 0068 6001          SACL DXR,0
0250 0069 CAFF          LACK >FF      * set flag.
0251 006A 607E          SACL FXMT
0252 006B CE26          RET           * return.
0253 *****
0254 *          ===== *
0255 *          Secondary data write routine 1. *
0256 *          ===== *
0257 * This routine is called when secondary communication *
0258 * occurs. It writes secondary data to DXR, and modifies *
0259 * the content of XVECT(117 page0) for continuing secondary*
0260 * communication. *
0261 *****
0262 006C 207 S1       LAC D2ND,0      * write DXR 2nd data.
0263 006D 6001          SACL DXR,0
0264 006E 2079          LAC VS2,0      * modify for next XINT.
0265 006F 6075          SACL XVECT,0
0266 0070 CE26          RET           * return.
0267 *
0268 *****
0269 *          ===== *
0270 *          Secondary data writing routine 2. *
0271 *          ===== *
0272 *
0273 * This routine is called when secondary communication *
0274 * occurs. It writes dummy data to DXR to ensure that *
0275 * secondary communication is not inadvertently *
0276 * initiated on the next XINT. It also modifies the *
0277 * content of XVECT for normal communication. *
0278 *****
0279 0071 CA00 S2       ZAC           * clear data for protection.
0280 0072 6001          SACL DXR,0      * of double secondary communication.
0281 0073 607F          SACL F2ND      * clear secondary flag.
0282 0074 CAFF          LACK >FF      * set xmit end flag.
0283 0075 607E          SACL FXMT,0
0284 0076 2077          LAC VNRM,0      * set normal communication vector.
0285 0077 6075          SACL XVECT,0
0286 0078 2073          LAC INTST,0     * enable all interrupts.
0287 0079 6004          SACL IMR,0
0288 007A CE26          RET           * return.

```

```

0289          *
0290          *****
0291          *           =====*
0292          *           Check secondary code.  destroy DP pointer.*
0293          *           =====*
0294          *           ACC.*
0295          *
0296          * This routine checks whether the data in DXMT (123 page0)*
0297          * has secondary code or not. If secondary code exists, *
0298          * then disable maskable interrupts except XINT, modify the*
0299          * contents of XVECT(117 page0) for secondary communi- *
0300          * cation, and set secondary flag. Note that we recommend*
0301          * calling this routine to send control words to the AIC.*
0302          *****
0302 007B C800 C2ND   LDPK 0           * data page pointer 0.
0303 007C CA03          LACK 03
0304 007D 606F          SACL TMPO
0305 007E 207B          LAC DXMT,0       * is this data secondary code
0306 007F 4E6F          AND TMPO
0307 0080 106F          SUB TMPO,0
0308 0081 F680          BZ C2ND1       * if yes, then next.
0309          0082 0084
0309 0083 CE26          RET           * else return.
0310          *
0311 0084 CAFF C2NDI  LACK >FF       * set secondary flag.
0312 0085 607F          SACL F2ND,0
0313 0086 CA20          LACK >20       * enable only XINT.
0314 0087 6004          SACL IMR,0
0315 0088 2078          LAC VSI,0       * modify vector address for secondary
0316 0089 6075          SACL XVECT,0    * communication.
0317 00BA 207B          LAC DXMT,0       * write primary data to DXR.
0318 008B 6001          SACL DXR,0
0319 00BC CE26          RET           * return.
0320          *
0321          *****
0322          *
0323          *           =====*
0324          *           Check first interrupt *
0325          *           =====*
0326          *
0327          * This routine checks if both first interrupts have *
0328          * occurred. If this routine is called after reset, it *
0329          * waits for both interrupts then returns. *
0330          *****
0331 008D 206D IGR     LAC FRE,0       * check first interrupt after
0332 008E F680          BZ IGR         * master reset.
0333          008F 008D
0333 0090 206C          LAC FXE,0
0334 0091 F680          BZ IGR
0335          0092 008D
0335 0093 CE26          RET
0336 0094

```

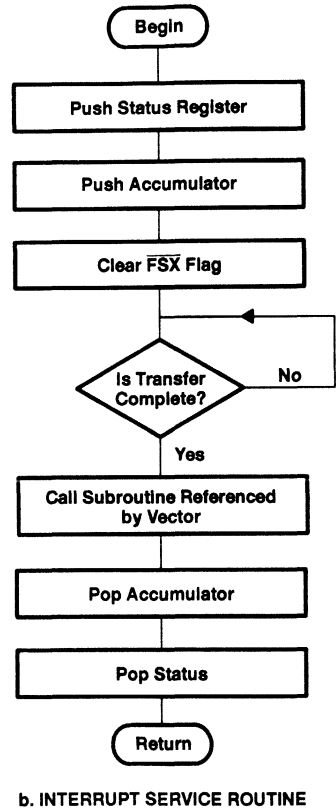
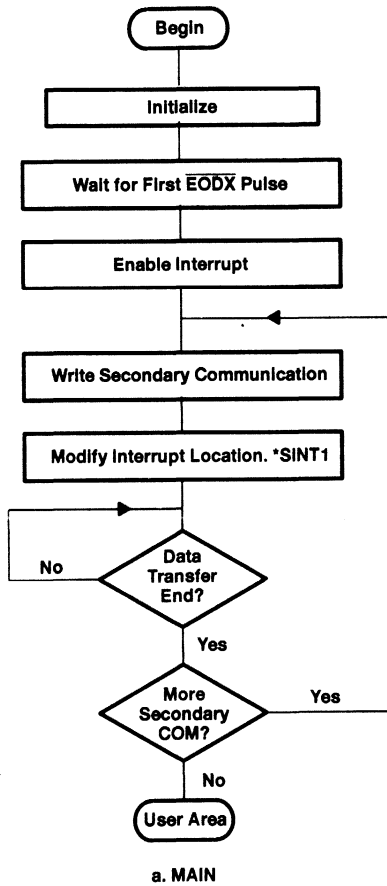
```

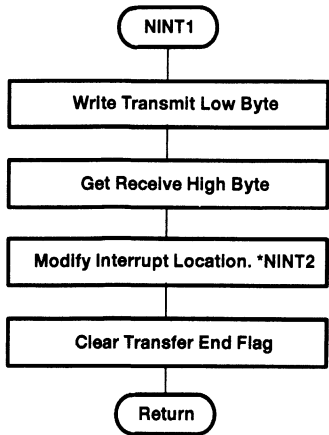
0337      *
0338      ****
0339      *          =====
0340      *          Ignore interrupt routine.
0341      *          -----
0342      * These routines are used so that the first RINT and
0343      * XINT after the %DSP reset can be ignored. They set
0344      * flags and modify each vector address to the normal
0345      * interrupt address but do not read or write to the
0346      * serial ports. Note that the first data that the AIC will
0347      * receive after the DSP reset is >0000.
0348      ****
0349 0094 CAFF IGNRR  LACK >FF
0350 0095 606D      SACL FRE,0
0351 0096 2076      LAC  VRCV,0      * set normal receive address.
0352 0097 6074      SACL RVECT,0    *
0353 0098 CE26      RET          * return.
0354      *
0355 0099 CAFF IGNRX LACK >FF
0356 009A 606C      SACL FXE,0
0357 009B 2077      LAC  VNRM,0      * set normal xmit address.
0358 009C 6075      SACL XVECT,0    *
0359 009D CE26      RET          * return.
0360      *
0361      END
NO ERRORS, NO WARNINGS

```

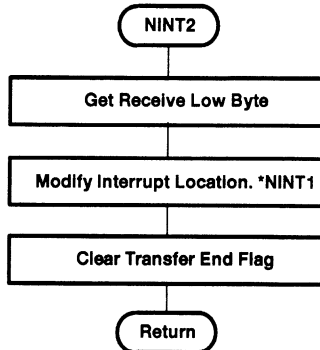

C TLC32040 and TMS320C17 Flowcharts and Communication Program

C.1 Flowcharts

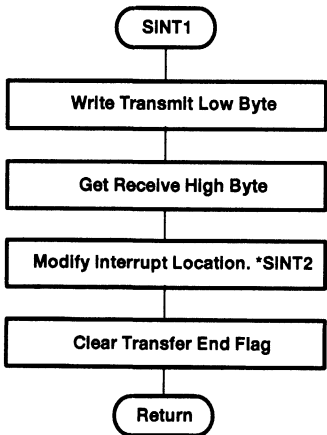




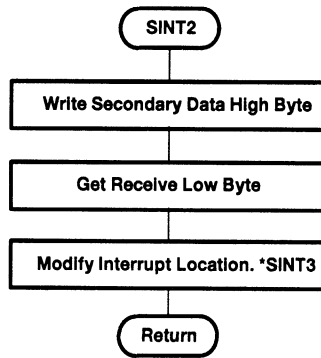
c. PRIMARY COMMUNICATION 1



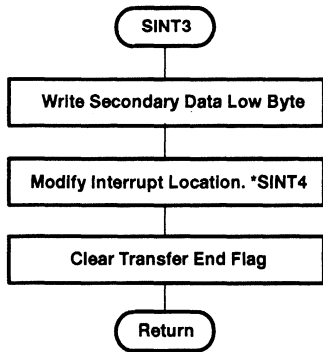
d. PRIMARY COMMUNICATION 2



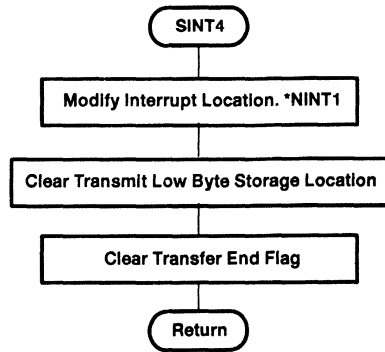
e. PRIMARY-SECONDARY COMMUNICATION 1



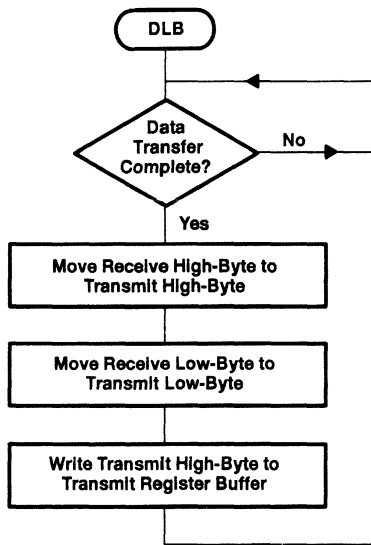
f. PRIMARY-SECONDARY COMMUNICATION 2



g. PRIMARY-SECONDARY COMMUNICATION 3



h. PRIMARY-SECONDARY COMMUNICATION 4



i. DIGITAL LOOPBACK

C.2 Communication Program List

```

0001      *****
0002      *
0003      *-----*
0004      *      TLC32040 to TMS320C17 Communication Program      *
0005      *                      version 1.2                      *
0006      *                      revised 7/22/88                  *
0007      *
0008      *                      by Hironori Okubo and Woody Rowand *
0009      *                      Texas Instruments                  *
0010      *                      (214) 997-3460                    *
0011      *-----*
0012      *
0013      * This program uses the circuit published in the Volume *
0014      * 3 of the Linear and Interface Circuit Applications    *
0015      * book with the following modification:                  *
0016      * *
0017      * 1. INT- of the TMS320C17 must be connected to        *
0018      * EODX- of the TLC32040.                                *
0019      *
0020      *
0021      * In this configuration, the program will allow the    *
0022      * TLC32040 to communicate with the TLC320C17 with the  *
0023      * restriction that all interrupts except INT- are       *
0024      * prohibited and only synchronous communication can     *
0025      * occur. The program allows the user two levels of     *
0026      * nesting in the main program; the remaining two levels *
0027      * are reserved for the interrupt vector and subroutines.*
0028      *
0029      * If desired, this program may be used with the TMS32011*
0030      * digital signal processor with the following change.   *
0031      * Since the TMS32011 has only sixteen words of data RAM *
0032      * on data page 1, all of the registers used by this    *
0033      * program should be moved to data page 0, except for    *
0034      * SSTSTK (the temporary storage location for the status *
0035      * register) which must remain on page %I (since the     *
0036      * SST instruction always addresses page 1).             *
0037      *
0038      *****
0039      0000 SSTSTK EQU >00 stack for status (SST) register.
0040      0001 ACHSTK EQU >01 stack for accumulator high (ACCH).
0041      0002 ACLSTK EQU >02 stack for accumulator low (ACCL).
0042      0003 RXEFLG EQU >03 xmit/receive in progress.
0043      0004 DRCV1 EQU >04 storage for high byte receive data.
0044      0005 DRCV2 EQU >05 storage for low byte receive data.
0045      0006 DXMT1 EQU >06 storage for high byte xmit data.
0046      0007 DXMT2 EQU >07 storage for low byte xmit data.
0047      0008 DXMT3 EQU >08 storage for high byte secndry data.
0048      0009 DXMT4 EQU >09 storage for low byte secndry data.
0049      000A VECT EQU >0A storage for interrupt vector addr.
0050      000B ANINT1 EQU >0B storage for normal xmit/rcv vect 1.
0051      000C ANINT2 EQU >0C storage for normal xmit/rcv vect 2.
0052      000D ASINT1 EQU >0D storage for secndry xmit/rcv vect 1.
0053      000E ASINT2 EQU >0E storage for secndry xmit/rcv vect 2.
0054      000F ASINT3 EQU >0F storage for secndry xmit/rcv vect 3.

```

```

0055 0000
0056 0010 ASINT4 EQU >10 storage for secndry xmit/rcv vect 4.
0057 0011 CNTREG EQU >11 storage for control register.
0058 0012 MXINT EQU >12 storage for xmit interrupt mask.
0059 0013 CLRX EQU >13 storage for xmit interrupt clear
0060 0014 CLRX1 EQU >14 storage for xmit intrpt clear/mask.
0061 0015 TEMP EQU >15 temporary register.
0062 00FF FLAG EQU >FF flag set.
0063 * -----
0064 * Branch to initialization routine.
0065 * -----
0066 0000 AORG >0000
0067 0000 F900 B INIT branch to initialization routine.
0001 0013
0068 00020069 *****
0070 * ----- *
0071 * Interrupt service routine. *
0072 * ----- *
0073 * *
0074 * To initiate secondary communication, change the *
* contents of VECT to the address of the secondary *
0075 * communication subroutine and store the *
0076 * in DXMT3 and DXMT4. *
0077 * *
0078 * *
0079 * e.g. *
0080 * LAC ASINTI modify VECT. *
0081 * SACL VECT *
0082 * | *
0083 * LAC H1 store high-byte of *
0084 * SACL DXMT3 secondary information in *
0085 * LAC H2 DXMT4 store low-byte in DXMT4. *
0086 * SACL DXMT4 *
0087 * *
0088 *****
0089 0002 AORG >02
0090 0002 6EOI INTSVC LDPK 1
0091 0003 7C00 SST SSTSTK push status register.
0092 0004 5801 SACH ACHSTK push accumulator high.
0093 0005 5002 SACL ACLSTK push accumulator low.
0094 0006 4813 OUT CLRXPAO make sure FSX-flag is clear.
0095 0007 4011 WAIT1 IN CNTREG,PAO read control register.
0096 0008 2011 LAC CNTREG,0 load accumulator with control
0097 0009 7912 AND MXINT reg mask-off xmit interrupt
0098 000A FF00 BZ WAIT1 flag loop until xmit interrupt
000B 0007 flag is recognized.
0099 000C
0100 *
0101 000C 200A LAC VECT load acc with interrupt vector.
0102 000D 7F8C CALA call appropriate xmit/rcv
routines
0103 000E 6501 ZALH ACHSTK pop accumulator high.
0104 000F 7A02 OR ACLSTK pop accumulator low.
0105 0010 7B00 LST SSTSTK pop status register.
0106 0011 7F82 EINT enable interrupts.
0107 0012 7F8D RET return to main program.

```

```

0108 0013
0109 *****
0110 * ===== *
0111 * Initialization after reset. *
0112 * ===== *
0113 * *
0114 * Data RAM locations >80 through >92 are reserved *
0115 * by this program. The user must set the status *
0116 * register at the end of this program with the SST *
0117 * command or a combination of SOVM, LDPK etc. *
0118 * *
0119 *****
0120 0013 7F81 INIT DINT disable interrupts.
0121 0014 6E01 LDPK 1 set data page pointer one.
0122 0015 7F89 ZAC clear registers.
0123 0016 6880 LARP 0
0124 0017 7083 LARK 0,RXEFLG+>80
0125 0018 50A8 SACL *+
0126 0019 50A8 SACL *+
0127 001A 50A8 SACL *+
0128 001B 50A8 SACL *+
0129 001C 50A8 SACL *+
0130 001D 50A8 SACL *+
0131 001E 50A8 SACL *+
0132 001F 5088 SACL *
0133 0020 4906 OUT DXMT1,PAI clear transmit registers.
0134 0021 4906 OUT DXMT1,PAI
0135 0022 7E04 LACK ?00000100
0136 0023 5012 SACL MXINT initialize xmit-int mask.prepare
0137 0024 7E01 LACK 1 for serial port initialization
0138 0025 5015 SACL TEMP and initialization of registers
0139 0026 6A15 LT TEMP containing 16-bit constants.
0140 0027 80A1 MPYK CLX1 initialize interrupt flag clear.
0141 0028 7F8E PAC
0142 0029 6713 TBLR CLRX
0143 002A 80A2 MPYK CLX2 initialize interrupt flag clear
0144 002B 7F8E PAC with interrupts disabled.
0145 00IC 6714 TBLR CLRX1
0146 002D 809D MPYK IGN
0147 002E 7F8E PAC
0148 002F 500A SACL VECT initialize interrupt vector.
0149 0030 8077 MPYK NINT1 save normal communication
0150 0031 7F8E PAC address to its storage.
0151 0032 500B SACL ANINT1
0152 0033 807D MPYK NINT2 save normal communication
0153 0034 7F8E PAC address 2 to its storage.
0154 0035 500C SACL ANINT2
0155 0036 8084 MPYK SINT1 save secondary communication
0156 0037 7F8E PAC address 1 to its storage.
0157 0038 500D SACL ASINT1
0158 0039 808A MPYK SINT2 save secondary communication
0159 003A 7F8E PAC address 2 to its storage.
0160 003B 500E SACL ASINT2
0161 003C 8090 MPYK SINT3 save secondary communication
0162 003D 7FBE PAC address 3 to its storage.
0163 003E 600F SACL ASINT3
0164 003F A095 MPYK SINT4 save secondary communication

```

```

0165 0040 CE14      PAC      address 4 to its storage.
0166 0041 6010      SACL      ASINT4
0167 0042
0168 *****
0169 * =====*
0170 * Synchronize high/low byte transmission.*
0171 * =====*
0172 * *
0173 * The time between FSX- interrupts is approximately *
0174 * ten microseconds (50 cycles). Wait for first if *
0175 * FSX-, this is the first interrupt, delay 60 cycles *
0176 * (past the second interrupt). If it is the second *
0177 * interrupt, no harm done.*
0178 * *
0179 *****
0180 0042 E014      OUT      CLRX1,PAO clear interrupt flags,disableint.
0181 0043 8011  IGNOR  IN      CNTREG,PAO read control register.
0182 0044 2011      LAC      CNTREG      wait
0183 0045 4E12      AND      MXINT      for
0184 0046 F680      BZ      IGNOR      FSX- flag.
0185 0047 0043
0185 0048
0186 0048 C014      LARK  0,20      wait 60 cycles (20 x 3 cycles) in
0187 0049 5500  IGNOR1 NOP      case FSX- int. is first of the
                                pair.
0188 004A FB90      BANZ  IGNOR1  if FSXI- int was the second, delay
0189 004B 0049
0189 004C
0190 004C E013      OUT  CLRX,PAO  anyway.
0191 004D
0192 004D CEDO      EINT      enable interrupt.
0193 *****
0194 * =====*
0195 * Main program (user area)*
0196 * =====*
0197 * *
0198 * This program allows the user two levels of nesting,*
0199 * since one level is used as stack for the interrupt and *
0200 * the interrupt service routine makes one subroutine *
0201 * call. User routines such as digital filtering, FFTS,*
0202 * and secondary communication judgement may be placed *
0203 * here. The number of instruction cycles between *
0204 * interrupts varies with the sampling rate. In the *
0205 * power-up condition this is approximately 500 cycles.*
0206 * *
0207 * In the example below, the first two transmissions send *
0208 * secondary information to the AIC. The first configures *
0209 * the TB and RB registers. The second configures the *
0210 * control register.*
0211 * *
0212 *****
0213 004E CA00  MAIN   ZAC      prepare first control word.
0214 004F 6006      SACL  DXMTI
0215 0050 CA03      LACK  >03
0216 0051 5007      SACL  DXMT2      should be xxxx xx11.
0217 0052 7E24      LACK  >24

```

```

0218 0053 5008 SACL DXMT3
0219 0054 7E92 LACK >92
0220 0055 5009 SACL DXMT4
0221 0056 200D LAC ASINT1 set VECT for secondary
0222 0057
0223 0057 500A SACL VECT communications.
0224 0058 4906 OUT DXMTI,PAI store first transmit byte in
0225 * transmit buffer.
0226 0059 7F89 ZAC
0227 005A 5003 SACL RXEFLG clear xmit/rcv end flag.
0228 005B 2003 MAIN1 LAC RXEFLG
0229 005C FF00 BZ MAIN1 wait for data transfer to
005D 005B complete.
0230 005E
0231 005E 7F89 ZAC prepare second control word.
0232 005F 5006 SACL DXMT1
0233 0060 7E03 LACK >03
0234 0061 5007 SACL DXMT2
0235 0062 7E00 LACK >00
0236 0063 5008 SACL DXMT3
0237 0064 7E67 LACK >67
0238 0065 5009 SACL DXMT4
0239 0066 200D LAC ASINT1
0240 0067 500A SACL VECT
0241 0068 4906 OUT DXMTI,PAL
0242 0069 7F89 ZAC
0243 006A 5003 SACL RXEFLG clear xmit/rcv end flag.
0244 *****
0245 * ===== *
0246 * Digital loop-back program *
0247 * ===== *
0248 * *
0249 * This program serves as an example of what can *
0250 * be done in the user area. *
0251 * *
0252 *****
0253 006B 2003 DLB LAC RXEFLG wait for data transfer to complete.
0254 006C FF00 BZ DLB
006D 006B
0255 006E
0256 006E 2004 LAC DRCV1 move receive data to transmit
0257 006F 5006 SACL DXMT1 registers.
0258 0070 2005 LAC DRCV2
0259 0071 5007 SACL DXMT2
0260 0072 4906 OUT DXMTI,PAL write first transmit byte to
0261 * transmit buffer.
0262 0073 7F89 ZAC
0263 0074 5003 SACL RXEFLG clear rcv/xmit-end flag.
0264 0075 F900 B DLB
0076 006B
0265 0077

```

```

0266 *****
0267 =====*
0268 * Normal interrupt routines.*
0269 * =====*
0270 *
0271 * These routines destroy the contents of the *
0272 * accumulator and the data page pointer, making it *
0273 * necessary to save these before the routines begin *
0274 *
0275 * Write the contents of DXMT2 to the transmit buffer*
0276 * and read the receive buffer into DRCV1.*
0277 *
0278 *****
0279 0077
0280 0077 4907 NINT1 OUT DXMT2,PAI write xmit-low to xmit register.
0281 0078 4104 IN DRCV1,PAI read rcv-data-high from rcv reg.
0282 0079 200C LAC ANINT2 prepare next interrupt vector.
0283 007A 500A SACL VECT
0284 007B 4813 OUT CLRX,PAO clear xmit interrupt flag.
0285 007C 7F8D RET
0286 007D 4105 NINT2 IN DRCV2,PAI read receive-data-low from rcv
reg.
0287 007E 200B LAC ANINTI prepare next interrupt vector.
0288 007F 500A SACL VECT
0289 0080 4813 OUT CLRX, PAO clear xmit interrupt flag.
0290 0081 7EFF LACK FLAG
0291 0082 5003 SACL RXEFLG set xmi&t/rcv end flag.
0292 0083 7F8D RET
0293 *****
0294 * =====*
0295 * Secondary interrupt routines*
0296 * =====*
0297 * These routines destroy the contents of the *
0298 * accumulator and the data page pointer.*
0299 *
0300 * The following routines write the low byte of *
0301 * the primary data word and the high and low byte *
0302 * of the secondary data word. They also read the *
0303 * A/D information in the receive registers.*
0304 *****
0305 0084 4907 SINT1 OUT DXMT2,PA1 write xmit-data-low to xmit reg.
0306 0085 4104 IN DRCV1,PA1 read receive-data-high from rcv
reg
0307 0086 200E LAC ASINT2 prepare next interrupt vector.
0308 0087 500A SACL VECT
0309 0088 4813 OUT CLRX,PAO clear xmit interrupt flag.
0310 0089 7F8D RET
0311 008A 4908 SINT2 OUT DXMT3,PAI write secondary-data-high to
xmit.
0312 008B 4105 IN DRCV2,PA1 read receive-data-low from rcv.
0313 008C 200F LAC ASINT3 prepare next interrupt vector.
0314 008D 500A SACL VECT
0315 008E 4813 OUT CLRX,PAO clear xmit interrupt flag.
0316 008F 7F8D RET
0317 0090 4909 SINT3 OUT DXMT4,PAI write secondary-data-low to xmit
0318 0091 2010 LAC ASINT4 prepare next interrupt vector.

```

```

0319 0092 500A SACL VECT
0320 0093 4813      OUT   CLRX,PAO      clear xmit interrupt flag.
0321 0094 7F8D      RET
0322 0095 200B SINT4 LAC   ANINT1      prepare next interrupt vector.
0323 0096 500A      SACL  VECT
0324 0097 4813      OUT   CLRX,PAO      clear xmit interrupt flag.
0325 0098 7F89      ZAC
0326 0099 5007      SACL  DXMT2      clear DXMT2 immediately to
eliminate
0327 009A 7EFF      LACK  FLAG      unexpected secondary
communications
0328 009B 5003      SACL  RXEFLG     set xmit/rcv end flag.
0329 009C 7FBD      RET
0330 *****
0331 * ----- *
0332 * Ignore first interrupt. *
0333 * ----- *
0334 * This routine is used to ignore the first data *
0335 * transmission and also to synchronize the AIC *
0336 * with the processor. *
0337 *****
0338 009D 200B IGN  LAC   ANINT1
0339 009E 500A      SACL  VECT
0340 009F 4813      OUT   CLRX,0
0341 00A0 7F8D      RET
0342 *****
0343 * *
0344 * CONTROL REGISTER INFORMATION *
0345 * *
0346 * SERIAL-PORT CONFIG. INT. MASK INT. FLAG *
0347 * | 1 0 0 0 1 1 1 0 | | 0 0 0 1 0 1 0 0 | *
0348 * 15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0 *
0349 * | * | | | ___INT *
0350 * | ___XF status * | | | ___FSR *
0351 * | * | * | ___FSX *
0352 * | * | * | ___FR *
0353 * *
0354 * (write 1's to clear) *
0355 *****
0356 00A1 8EIF CLXI DATA >8EIF
0357 00A2 8EOF CLX2 DATA >8EOF
0358 END
NO ERRORS, NO WARNINGS

```



```

0317 009D 200B IGN  LAC      ANINT1
0318 009E 500A      SACL     VECT
0319 009F 4813      OUT     CLRX,0
0320 00A0 7F8D      RET
0321 *****
0322 *
0323 *      CONTROL REGISTER INFORMATION      *
0324 *
0325 *      SERIAL-PORT CONFIG.  INT. MASK INT. FLAG      *
0326 *      | 1 0 0 0 1 1 1 0 | | 0 0 0 1 0 1 0 0 |      *
0327 *      15 14 13 12 11 10 9 8 7 6 5 4 3 2 1 0      *
0328 *      | _____ | | | | _____INT      *
0329 *      | _XF status  | | | | _____FSR      *
0330 *      | _____FSX      *
0331 *      | _____FR      *
0332 *
0333 *      (write 1's to clear)      *
0334 *****
0335 00A1 8E1F CLXI  DATA  >8EIF
0336 00A2 8EOF CLX2 DATA  >8EOF
0337      END
NO ERRORS, NO WARNINGS

```


***Designing with the TLC320AC01
Analog Interface for DSPs***

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1 INTRODUCTION

This application report was prepared by John Walliker and Julian Daley of University College London. It is based on their experience of using the device as part of a specialized signal processing hearing aid. However the techniques described, for both the analog and digital interfaces, are appropriate for a wide variety of applications.

Measurements of performance quoted in this application note are those achieved with the particular samples and test set-up. For the full device specification see the TLC320AC01 data manual, reference SLAS057A.

Some features of the TLC320AC01 were not used in this design and therefore have not been covered here. They are phase adjustment and the use of multiple devices.

1.1 Overview of Device

The TLC320AC01 is a 14-bit resolution, audio frequency (approximately 12-kHz bandwidth) analog interface for DSP with integral anti-aliasing and reconstruction filters. It has a synchronous, serial, digital interface designed for ease of connection to many DSP chips.

The internal circuit configuration and the performance parameters, such as input source, sampling rate, filter bandwidths and gain, are determined by writing in control information to eight data registers. These registers are used to set-up the device for a given mode of operation and given application. The ADC channel and the DAC channel operate synchronously and data is transferred in 2's complement format.

The anti-aliasing filter is a switched-capacitor low-pass filter with a sixth-order elliptic characteristic. The high-pass is a single-pole filter, which can be switched out if required. There is a 3-pole continuous-time filter that precedes the switched-capacitor filter to eliminate aliasing caused by sampling in the switched-capacitor filter.

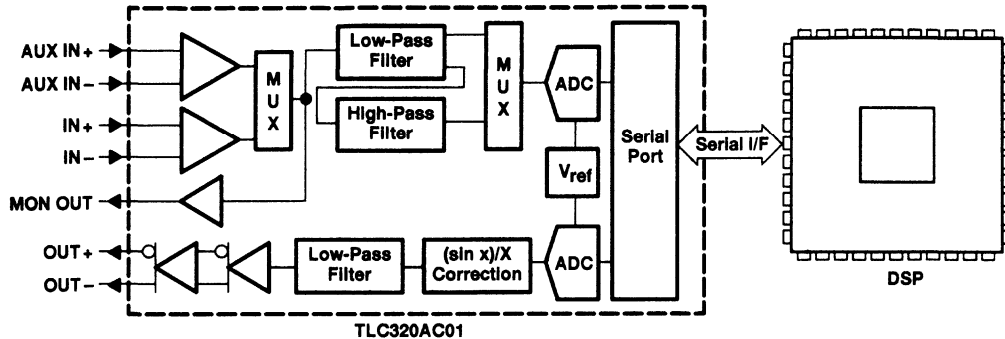
The output-reconstruction filter is also a switched-capacitor low-pass filter with a sixth-order elliptic characteristic and it is followed by a second-order $(\sin x)/x$ correction filter. This is followed by a three-pole continuous-time filter to eliminate images caused by sampling in the switched-capacitor filter.

There are three basic modes of operation available:

- Stand-alone analog-interface mode, where the TLC320AC01 generates the shift clock and the frame sync for the data transfers and is the only AIC used.
- Master-slave mode, where the master TLC320AC01 generates the shift clock and the frame sync and the rest are slaves to these signals.
- Linear-codec mode, where the shift clock and the frame sync are generated externally and the timing can be any of the standard codec timing patterns.

The TLC320AC01 is available in a standard 28-pin plastic J-lead chip carrier (FN suffix) and a 64-pin plastic-quad-flat-pack (PM suffix) which is only 1,5 mm thick, making it suitable for use in portable systems.

The device has a maximum power dissipation of 110 mW in the active mode and 10 mW in the power down mode. It runs from a single 5-V supply, both for digital and analog circuitry. This is particularly useful for portable equipment, but does require extra care in the design of the analog input and output stages.



- TLC320AC01**
- 14-bit A/D converter
 - 14-bit D/A converter
 - Antialiasing filter
 - Anti-imaging filter
 - (sin x)/x correction
 - Input and output amplifiers
 - Programmable bandwidth, sampling rate, gain, I/P source
 - Single 5 V supply
 - 70 dB typical signal to noise+distortion ratio
 - 100 mW typical power consumption
 - Analog bandwidth up to 10.8 kHz

Figure 1. TLC320AC01 Analog Interface for DSP

2 ANALOG INPUT

2.1 Signal-to-Noise and Signal-to-Distortion Measurements

With the internal gain of the TLC320AC01 set to 0 dB, a full scale signal corresponds to 6 V peak-peak at the analog input (equivalent to $6/(2\sqrt{2}) = 2.12$ V RMS).

The input signal-to-noise ratio of the TLC320AC01 can be expressed in terms of the number of least significant bits (LSB) of noise present in the digital signal, when both its inputs are connected to V_{MID} . The RMS value of the noise was measured on the test boards at 0.5 LSB. This corresponds to a noise voltage of approximately 180 μ V RMS at the input (i.e., a signal-to-noise ratio of 81 dB). The intermodulation measurements are shown in Figure 2. The stimulus was the sum of a 1 kHz signal at -6 dB referred to full scale plus a 1.2 kHz signal at -12 dB referred to full scale. Distortion products are approximately 80 dB down throughout the pass band. The low frequency peaks that can be seen are multiples of 50 Hz interference.

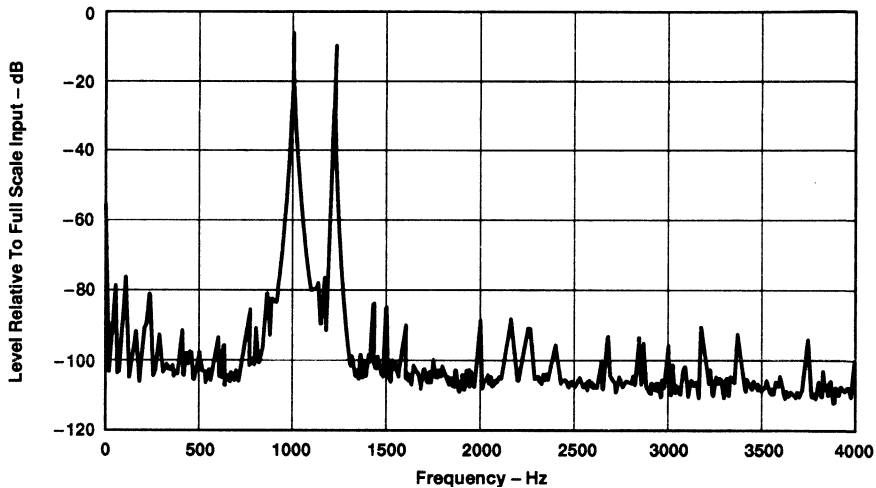


Figure 2. ADC Noise and Distortion Measurement

In the test circuit, the dc accuracy on the samples measured was 14 LSB, equivalent to 5 mV of dc offset.

2.2 Input Preamp Design

2.2.1 Noise Considerations

In order that the input preamp does not significantly affect the noise performance of the system, it should produce a noise level at least 6 dB below the TLC320AC01, (i.e., less than 90 μ V RMS) at the TLC320AC01 input.

Consider the case of a microphone producing 20 mV peak-to-peak at the maximum sound level, a preamp is needed with a gain of $6\text{ V}/20\text{ mV} = 300$ to get a full scale input at the ADC. So the input noise produced by the preamp must be less than $90\text{ }\mu\text{V}/300 = 300\text{ nV RMS}$.

For a preamp with a bandwidth of 10 kHz the input noise voltage should be less than

$$\frac{300\text{ nV}}{\sqrt{10\text{ kHz}}} = 3\text{ nV}/\sqrt{\text{Hz}}$$

This noise is made up of the operational amplifier's noise voltage combined with the thermal noise of the equivalent series resistance of the input source. Resistor values need to be carefully chosen, since a 10 k Ω resistor produces thermal noise of $14\text{ nV}/\sqrt{\text{Hz}}$ at room temperature. (spectral noise voltage density for a resistor is given by $\sqrt{4KTR}$, where K is Boltzman's constant, T is the absolute temperature and R the resistance). In this case, a 100- Ω resistor was chosen

(producing a thermal noise of $1.4 \text{ nV}/\sqrt{\text{Hz}}$ at room temperature). A MAX410 operational amplifier was chosen for the first gain stage as this has a noise voltage of $2.4 \text{ nV}/\sqrt{\text{Hz}}$. Noise voltages combine as the root of the sum of the squares, so the total noise is given by:

$$\sqrt{(2.4 \text{ nV}^2 + 1.4 \text{ nV}^2)} = 2.8 \text{ nV}/\sqrt{\text{Hz}}$$

The gain is split between two operational amplifiers. The first, low noise, operational amplifier configured as a noninverting amplifier with a gain of 100, followed by a second noninverting stage with a gain of three. This second operational amplifier does not need such a low noise voltage specification since its input noise is only being amplified by three. The TLC2272 dual operational amplifier, which has a noise voltage of $9 \text{ nV}/\sqrt{\text{Hz}}$, is chosen for its low power consumption, low input offset and well behaved performance under overload. (These operational amplifiers do not exhibit the behavior of BIFETs which can produce phase reversal of the output when the inputs go out of negative common mode range).

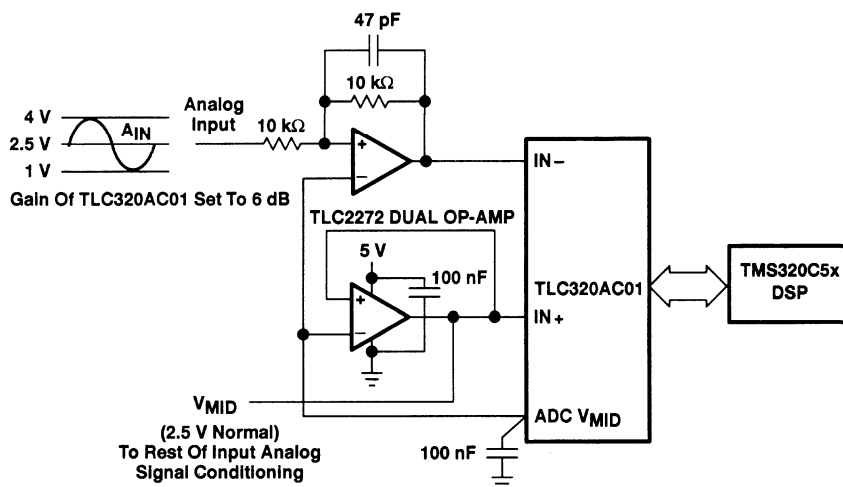


Figure 3. V_{MID} Referenced Input Circuit

2.2.2 V_{MID} Referenced Input Circuit Configuration

The configuration of the input circuitry requires extra care since all internal signals are referenced to V_{MID} rather than ground, to allow single supply operation. The PSRR at the internally generated V_{MID} point is low, so it is important that both the differential inputs are referenced to V_{MID} with any noise on V_{MID} appearing equally on both inputs. There are two ways of fulfilling this criterion. The first is to reference the whole input circuit to V_{MID} (using this as a virtual ground) as shown in Figure 3.

This configuration has the advantage of simplicity although there are some drawbacks. The buffered V_{MID} point has to be capable of driving the virtual ground and since many operational amplifiers are unhappy driving large capacitive loads this problem must not be overlooked. The TLC2272 is a good choice for this application. The input needs to be referenced to V_{MID} , which may cause a problem if interfacing to an externally powered, ground referenced signal. In this case the input needs to be ac coupled.

2.2.3 0-V Referenced Input Circuit Configuration

The second method is to level shift the signal just before the ADC inputs as shown in Figure 4. In this circuit, the preamp input is referenced to 0 V. This circuit allows a full range input swing ($V_{MID} \pm 1.5 \text{ V}$ on each input) for an input signal of $\pm 1.5 \text{ V}$. Any noise on V_{MID} appears equally on both differential inputs and is therefore cancelled. The common mode range of the inputs does not exceed the supply rails, so V_{MID} noise must not take the input signal outside the supply rails. The eight resistors can conveniently be in one thin film resistor package, giving good matching of resistor values and hence good power supply rejection ratio (PSRR) and dc accuracy. Amplifier A1 must have $\pm 5 \text{ V}$ or greater power rails but A2 to A4 only need a single 5-V rail.

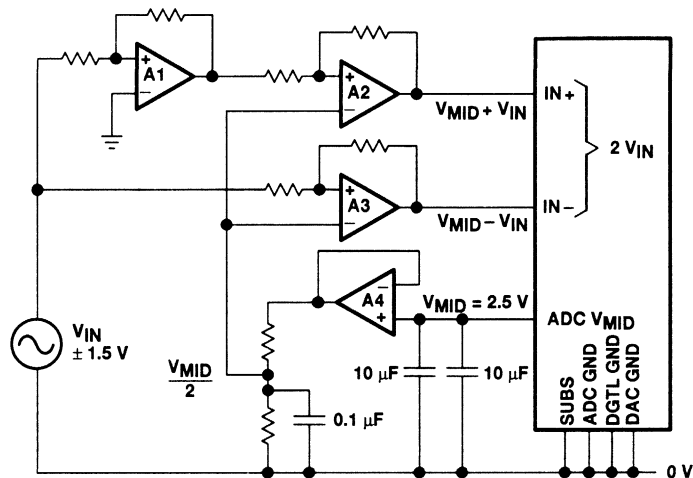


Figure 4. 0-V Referenced Input Circuit

2.2.4 Gain Control

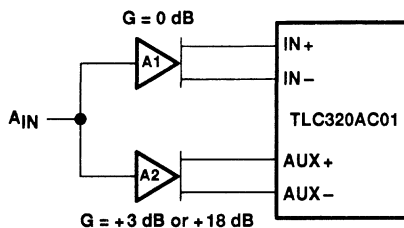
The internal preamp of the TLC320AC01 has software selectable internal gain of 0 dB, 6 dB or 12 dB plus a squelch mode (-60 dB). With 0 dB gain, plus or minus full scale result is given for a differential input of ± 3 V. With a single ended input configuration (one input tied to V_{MID}), this would not allow plus or minus full scale before the operational amplifiers run out of headroom, so the gain must be set to 6 dB or 12 dB which would give plus or minus full scale with ± 1.5 V and ± 0.75 V, respectively, at the TLC320AC01 input.

Most of the input noise is associated with the converter itself, rather than the input amplifiers or multiplexers. Therefore, the signal-to-noise ratio is hardly affected by the chosen input gain. However, it is easier to ensure good rejection of power supply noise coupled through V_{MID} at low gains.

The TLC320AC01 has two sets of differential inputs, IN and AUX IN which can be individually selected (or both selected simultaneously for mixing).

If more gain settings are required, a combination of software switching of input source and input gain coupled with an extra hardware gain stage (see Figure 5) allows six software selectable gain steps as shown in the following table.

EXTERNAL GAIN 3 dB			EXTERNAL GAIN 18 dB		
NORM/AUX INPUT	INTERNAL GAIN (dB)	TOTAL GAIN (dB)	NORM/AUX INPUT	INTERNAL GAIN (dB)	TOTAL GAIN (dB)
NORM	0	0	NORM	0	0
AUX	0	3	NORM	6	6
NORM	6	6	NORM	12	12
AUX	6	9	AUX	0	18
NORM	12	12	AUX	6	24
AUX	12	15	AUX	12	30



Internal Gain Settings 0 dB, 6 dB, 12 dB

Figure 5. Input Circuit for 6 S/W Selectable Gain Settings

2.3 Layout and Grounding

Although earthing and PCB layout do not seem to be too critical for this device, it is good practice to ensure that the ground current from sensitive devices such as the ADC does not flow in the same copper as currents from other devices. This means having a central ground point near the device or using power planes with splits where necessary to isolate return current from other devices.

The substrate (SUBS) should be connected to ADC ground. Failure to do so can result in noisy and unstable operation. The circuit should be well decoupled for low and high frequencies to minimize noise injection from the supplies.

2.4 Power Supply

With a master clock frequency of 10 MHz, the TLC320AC01 samples typically drew 10 mA at 5 V with default register values. The supply current depends principally on the filter clock frequency. If a negative supply is needed for operational amplifiers, etc., it may be convenient to generate it using a negative voltage converter. Since the negative supply generally draws little current this is a feasible solution and avoids the need for a second battery in portable systems. The ICL7660 needs no external inductors and is available in an 8-pin small outline package. As the internal oscillator of the ICL7660 free runs at about 10 kHz, noise generated from this oscillator can find its way into the ADC input, often beating with the sampling clock creating a whirring type noise. It is however possible to lock this oscillator to the ADC clock by linking the conversion complete signal to the oscillator input on the ICL7660. Coupling via a 100-pF capacitor allows the converter to free-run if the ADC is not operative (e.g., during start-up). Any noise that now gets coupled into the ADC will be the same for each sample, creating a dc result that is much easier to deal with. Alternatively the TLE2682 provides a negative rail generator supplying up to 100 mA (which can be phase locked) plus a dual operational amplifier in one 16-pin wide body SO package).

2.5 Sampling Rate and Filters

Within limits, the sampling rate of the device (both ADC and DAC are inherently synchronous) can be set under software control. If the DAC is not used then the ADC can run at up to 43.2k samples/sec. However, if the DAC is to be used the sampling rate must be limited to 25k samples/sec.

The anti-aliasing filters (switched capacitor type) track the sampling rate by setting the corner frequency of the filter to some fraction of the sampling rate. This allows for the possibility of sub-Nyquist sampling, which should be avoided in most cases. The ratio of sampling rate to anti-aliasing filter corner frequency is set by the B register value (REG_B). The anti-aliasing corner frequency is set by the A register value (REG_A) within the TLC320AC01.

Conversion rate is given by:

$$f_{\text{sample}} = \frac{f_{\text{MCLK}}}{(2 \times \text{Reg}_A \times \text{Reg}_B)}$$

The anti-aliasing corner frequency is given by:

$$f_{lp} = \frac{f_{MCLK}}{80 \times Reg_A}$$
$$\frac{f_{sample}}{f_{lp}} = \frac{40}{Reg_B}$$

To satisfy Nyquist's sampling theorem:

$$\frac{f_{sample}}{f_{lp}} \geq 2$$
$$\therefore Reg_B \leq 20$$

The default of 18 for the B register gives $f_{sample}/f_{lp} = 2.2$. This ensures that energy above the Nyquist frequency is well into the filter's stop band.

The product of the A and B registers must be greater than 65 to allow for 17 serial clock cycles between conversions (16 data bits plus one extra cycle for frame sync in master or standalone mode). The B register must not be less than 10, since the ADC conversion takes 10 B register counts to complete. The A and B registers have a maximum value of 255.

2.5.1 High-Pass Filter

The TLC320AC01 also has a high-pass filter which can be used to attenuate subsonic noise and remove dc offsets. The importance of subsonic noise filtering should not be underestimated. For example: air conditioning systems are a notorious source of low frequency noise and a slamming door can produce extremely high levels of subsonic energy. The filter in the TLC320AC01 has a corner frequency of $f_s/200$ and a slope of 6 dB per octave. The corner frequency cannot be changed independently of the sampling frequency.

3 ANALOG OUTPUT

As previously mentioned, the maximum sample rate for the DAC, at 25 kHz, is lower than for the ADC. This limits the bandwidth of the output signal to less than 12.5 kHz.

3.1 Signal-to-Noise and Signal-to-Distortion Ratio

Figure 6 shows the result of intermodulation distortion measurements for the DAC made on the test boards. The noise floor can be seen at approximately -90 dB in the pass band, falling to approximately -108 dB at frequencies above $f_s/2$. There are some distortion products in the pass band at approximately -85 dB. The double peaks at approximately 7 kHz and 9 kHz are images of the signal that have been only partially attenuated by the reconstruction filter. Images are the digital to analog equivalents of aliases in analog to digital conversion. They occur at frequencies given by:

$$f_{\text{image}} = N f_s \pm f_{\text{in}}$$
$$N = 1, 2, 3 \dots$$
$$f_s = \text{sampling frequency}$$

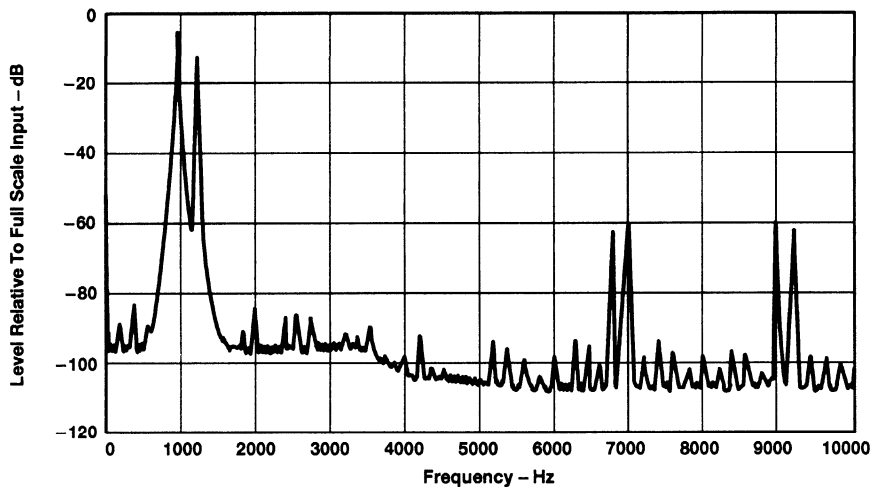


Figure 6. DAC Noise and Distortion Measurements

If the images are too large for a given application they can be removed by continuous-time low-pass filtering at the output of the DAC. The size of the images reflects the 45 dB stop-band attenuation of the reconstruction filter.

3.2 Voltage Swing and PSRR

The voltage swing at the differential output is ± 6 V for a full scale output. There are software selectable attenuators giving outputs of 0 dB, -12 dB and a squelch mode of -60 dB. Although there is not a large improvement in SNR ratio by using a differential output stage, it has the added advantage of increasing the PSRR and allowing level shifting to a ground referenced output without having to ac couple the signal. Using a thin film resistor pack for the differential amplifier gives the well matched resistors needed for good common mode rejection and accurate gain. Using a differential amplifier in this way the PSRR was improved from 49 dB to 53 dB (see Figure 7).

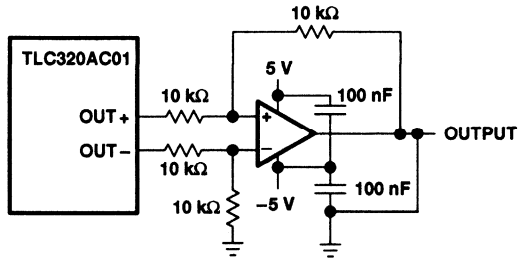


Figure 7. Differential to Single Ended Output Circuit

3.3 $(\sin x)/x$ Correction

$(\sin x)/x$ error arises because the output from a digital-to-analog converter is held constant between samples rather than smoothly joining them up. The TLC320AC01 has a $(\sin x)/x$ correction filter. It gives a correct response for a B register value of 15, which gives a ratio of sample rate to ADC anti-aliasing filter of 2.67. But as it does not track the B register, other values for the B register will produce an error in the magnitude of a given output frequency. Figure 8 shows a graph of calculated error versus frequency for various values of B register with a master clock of 10 MHz and sample rate of approximately 8 kHz. Other values can be calculated using the equation given in section 2.15.7 of the TLC320AC01 data manual.

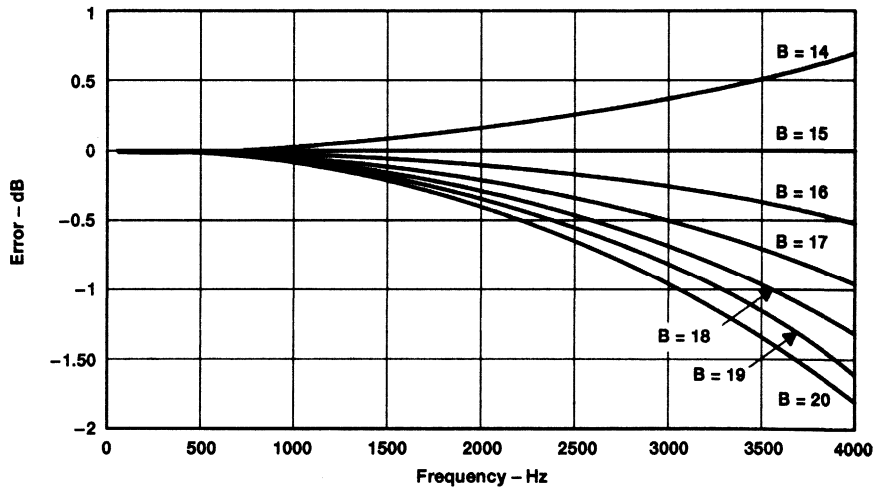


Figure 8. $(\sin x)/x$ Error

4 DIGITAL DESIGN CONSIDERATIONS

4.1 DSP Serial Interface

The TLC320AC01 can be connected directly to the synchronous serial port of a TMS320C25 as shown in Figures 6–1 and 6–3 of the TLC320AC01 data manual. Interfacing the TMS320C50 family requires some caution because the CLKOUT signal will usually exceed the maximum 15 MHz MCLK frequency of the TLC320AC01. So a divider is required. Most makes of DSP chip support the synchronous serial interface and should connect directly to the TLC320AC01.

4.1.1 Maximum Clock Rate

It is highly desirable that the DSP chip and TLC320AC01 are clocked from a common master oscillator. This ensures that the digital noise which is often coupled into the ADC and DAC of the TLC320AC01 in miniature systems is aliased to a stable frequency, preferably dc. Texas Instruments has found that the signal-to-noise ratio can be degraded by as much as 6 dB in a breadboard system when independent clocks are used compared with a fully synchronous system.

A convenient way of phase locking the TLC320AC01 to the processor is to drive the MCLK input of the TLC320AC01 from the CLKOUT of a TMS320C25 or TMS320C50 or from the H1 or H3 output of a TMS320C30. However, because of the higher speed of the TMS320C50 an external one or two stage divider must be used to lower the CLKOUT frequency (which can be between 20 MHz and 40 MHz depending on which speed grade of processor is used) to 15 MHz or less. A SN74ACT74 was chosen for its high maximum clock frequency, relatively low power consumption and availability in surface mount package. The divider power supply current was measured at 6.5 mA at 5 V and 3.17 mA at 3 V when dividing by 2 at 20 MHz; and 20.3 mA at 5 V and 9.6 mA at 3 V when dividing by 4 at 40 MHz.

4.1.2 Synchronization of Negative Rail Generator

If switching power supplies are used in the system, for example to generate a negative supply rail, it is advantageous to phase lock the switching frequency to the sampling frequency. The EOC output from the TLC320AC01 is close to a square wave for reasonable sampling frequencies and can be connected to the OSC pin of a ICL7660 negative supply generator through a small (100 pF) capacitor to force the normally free running oscillator. The small capacitor allows the ICL7660 to free run in the absence of an EOC signal. The ICL7660 divides this signal by two internally, so that power supply ripple is at exactly the Nyquist frequency and hence appears as a small dc offset rather than as an unstable whistle.

4.1.3 Edge Timing

It is important to ensure that the rise and fall times of the serial clock signal between the codec and DSP chip are within specification, particularly if level shifting circuits are used for mixed 5 V and 3 V operation. Failure to do so can result in data or frame sync signals being sampled on the wrong clock edge, causing erratic errors. The shift clock output rise and fall times for the TLC320AC01 in master mode are specified at 19 ns maximum and 13 ns typical in the data manual. The maximum serial clock input rise and fall times for the TMS320C25 are 25 ns, and for the TMS320C30 and TMS320C50 are 8 ns. While it might seem from these specifications that the TLC320AC01 cannot satisfactorily drive the TMS320C30 or TMS320C50 without buffering, these devices do work reliably together as long as very short connections are used.

In order to discover whether the system was operating with a reasonable safety margin, the rise and fall times of SCLK were measured. The measurements were made using a LeCroy oscilloscope sampling at 1 GHz and a FET probe with SCLK from the TLC320AC01 driving the parallel inputs CLKX and CLKR on the TMS320C50. The PCB track length was approximately 10 cm and the width 0.25 mm. The results (shown below) were well within the requirements of the TLC320C50.

	V _{DD} = 5 V	V _{DD} = 4 V
Rise time (0.8 V to 2 V)	2.3 ns	4.1 ns
Fall time (2 V to 0.8 V)	4.4 ns	5.6 ns

4.2 Hardware Design of TMS320C50 Based DSP System

A relatively simple yet powerful DSP system can be built using a TMS320C50 family digital signal processor and a TLC320AC01 AIC, as shown in Figure 9. The circuit shown is a simplified version of one that we have used extensively. It can readily be expanded to include parallel input and output ports. The TMS320C50 has 10K words of on-chip RAM, allowing complex algorithms to be implemented without the need to use external RAM. Some means of program storage is needed. A pair of 8-bit wide 1-Mbit flash EPROMs (N28F001BX-B120 from Intel) were used which completely fill the program and data address spaces, allowing the use of very large data tables. They have the advantages of reasonably low power consumption, especially when idle, the ability to be reprogrammed in-circuit or in a standard programmer (if socketed) and have a hardware protected boot block. The boot block is an 8K byte segment starting at address zero which can be protected against erasure by opening a switch. This allows the EPROM programming algorithm to be safely stored within the EPROM itself, downloaded to on-chip memory and executed from there to reprogram the rest of the flash EPROM with data transmitted through one of the serial ports. This is very convenient when portable equipment is to be reprogrammed in the field, especially when surface mounted devices are permanently soldered into the circuit. The initial bootstrap code can either be loaded using a standard programmer before assembly, or afterwards using the XDS510 in-circuit emulator interface which is brought out to a 14-pin header. These flash EPROMs have an internal state machine to control the erasure and programming algorithms. This is very important, not only because it simplifies programming, but it ensures that the essential precharge step before erasure is applied to all locations. This cannot easily be done with earlier generations of flash memory because those addresses that overlap internal registers and memory cannot easily be accessed. 100 k Ω pull-up resistor packs were used on the data bus and serial port signals to minimize power consumption when the bus is in a high impedance condition, which is the normal condition when executing from on-chip RAM.

A standard, 40 MHz, third overtone crystal oscillator was used to clock the TMS320C50. Exactly 8 kHz or 16 kHz sampling frequencies cannot be obtained with a 40 MHz MCLK. If this is a requirement, an MCLK of 41.475 MHz should be used. A 2.2 μ H surface mount inductor blocks oscillation at the fundamental frequency of the crystal. The 330 k Ω resistor biases the on-chip oscillator inverter. Some care is needed in the choice of this value to ensure stable operation and reliable start-up. With the component values shown, the oscillator starts at a supply voltage of approximately 2 V and is stable up to the absolute maximum of 7 V. Alternatively, CLKMD2 of the TMS320C50 can be grounded and an external 20 MHz clock fed into CLKIN2. This provides a divide by 1 option whereby the CPU clock operates at the same 20-MHz frequency. The 20 MHz, CLKOUT1 signal from the TMS320C50 is divided by two using half a SN74ACT74 D-type flip-flop to provide a 10 MHz MCLK to the TLC320AC01.

4.3 Battery Operation

4.3.1 Reset Considerations

The TLC320AC01 undergoes a power-on reset when V_{DD} falls below 4 V with the samples tested. In battery powered systems it is important to ensure that the supply never dips this low, otherwise all the programmed registers will return to their default values. To guard against undetected resetting, the system supply should be monitored, using a comparator as shown in Figure 9 or a supply voltage supervisor such as the TL7702B. Also, one of the registers that has been changed from its default should periodically be read back and checked.

4.3.2 Interfacing to a 3-V DSP Processor

There is a strong incentive to operate DSPs at 3 V or 3.3 V to save power. As the TLC320AC01 resets at a V_{DD} of about 4 V, separate power supplies and level shifting circuits must be used. The signals from a true CMOS DSP such as the TMS320C50 swing from 0 to V_{DD} , that is from 0 V to 3 V. As this is greater than the 2.2-V logic high threshold of the TLC320AC01, all signals from the DSP to the TLC320AC01 can be directly connected, provided that the 5-V supply rises and falls faster than the logic supply at switch on and off, respectively. If the power sequence cannot be guaranteed, the TLC320AC01 inputs should be protected with a series resistor of about 3.3 k Ω compensated with a parallel capacitor of about 1 nF. There will be a small increase in I_{DD} of the TLC320AC01 compared with driving from 0 V to 5 V due to simultaneous conduction by both FETs in the input circuits. Signals from the TLC320AC01 to the DSP cannot be directly connected, however. The simplest interface circuit is a series resistor, to limit the current flowing through the upper protection diode, with parallel compensating capacitor to preserve the rise and fall times, as shown in Figure 10.

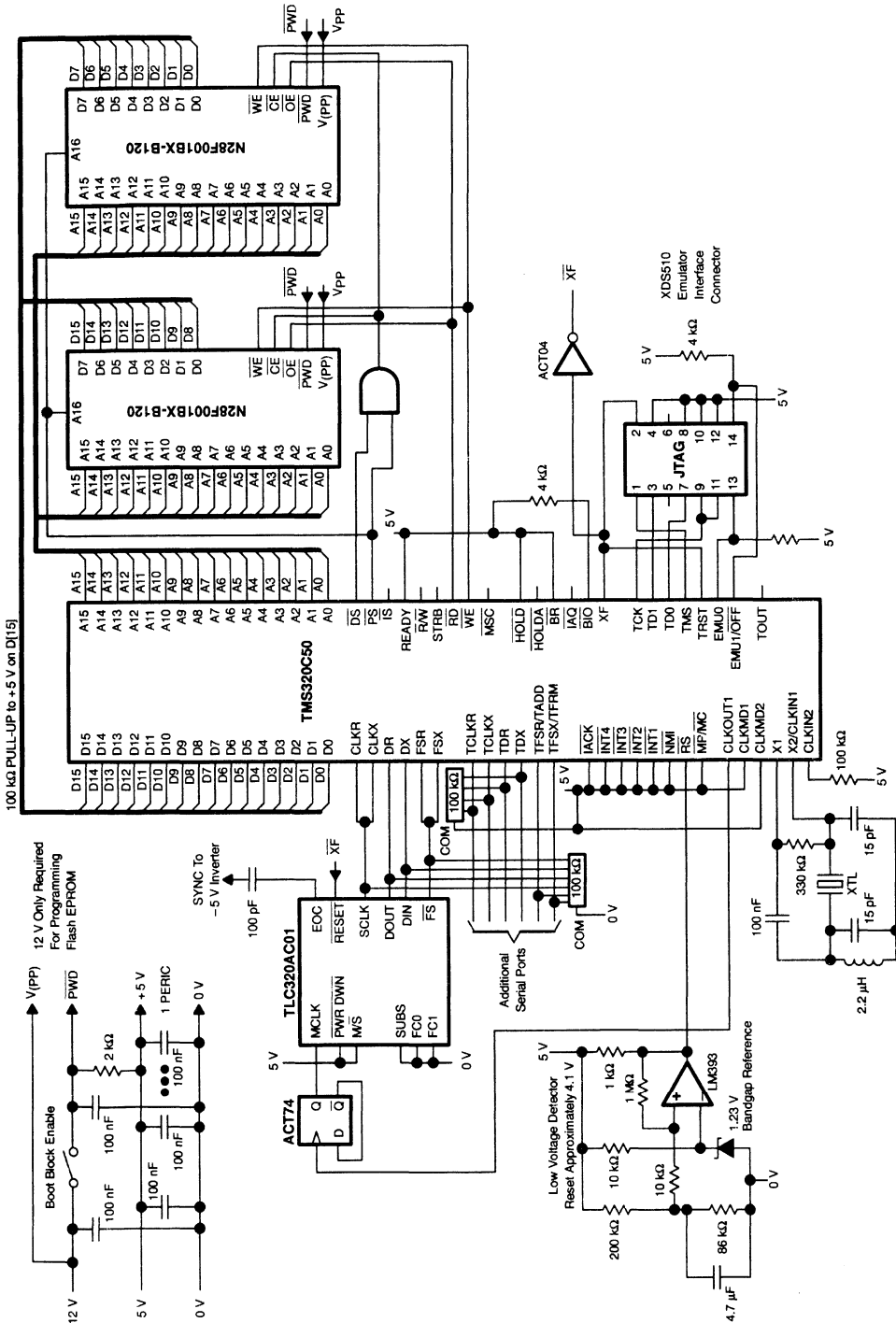


Figure 9. TLC320AC01 to TMS320C50 Hardware Schematic

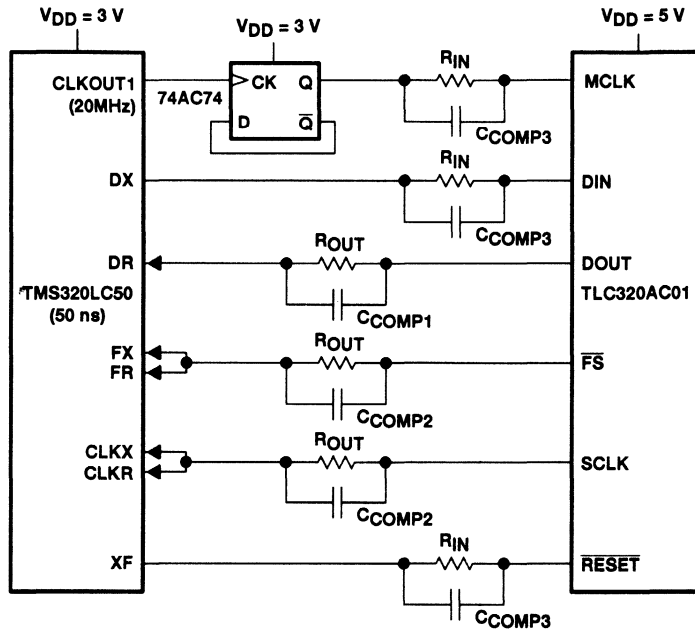


Figure 10. Interfacing to 3-V DSP

4.3.3 Calculation of Interface Component Values

Assuming that a transient input current through the protection diodes of 1 mA at power-up is safe for both devices and that the order of rise and fall is unknown. Then, 3.3 k Ω resistors (R_{IN}) in series with the TLC320AC01 inputs and 5.6 k Ω resistors (R_{OUT}) in series with the outputs provide full protection.

To calculate the appropriate compensation capacitor for signals from the TLC320AC01 to the TMS320C50, treat the parallel combination of C_{IN} and C_{STRAY} in conjunction with C_{COMP} as a capacitive divider where:

$$V_{OUT} = \frac{V_{IN} C_{COMP}}{C_{COMP} + C_{IN+STRAY}}$$

rearranging:

$$C_{COMP} = \frac{C_{IN+STRAY} V_{OUT}}{V_{IN} - V_{OUT}}$$

Substituting for worst case power supplies of 3.3 V and 4.5 V with one TMS320C50 input load of 15 nF and 10 pF stray capacitance:

For one input:

$$C_{COMP1} = \frac{(15 + 10) \times 3.3}{4.5 - 3.3} \approx 68 \text{ pF}$$

For two inputs:

$$C_{COMP2} = \frac{(15 + 15 + 10) \times 3.3}{4.5 - 3.3} \approx 120 \text{ pF}$$

These capacitor values should not be greatly increased because the input protection diodes of the TMS320C50 would then be driven into transient conduction on each rising logic edge.

The same method is applied to calculate the compensation capacitor for signals going to the TLC320AC01 (e.g., $\overline{\text{RESET}}$, MCLK and DIN). Assume a TLC320AC01 input capacitance of 5 pF and 10 pF stray capacitance, a worst case V_{DD} for the TMS320C50 and TLC320AC01 input threshold of 2.2 V.

$$C_{\text{COMP3}} = 68 \text{ pF}$$

This is a minimum value. C_{COMP} should be as large as possible for lowest power consumption and best noise margin. The maximum value of C_{COMP} depends upon the DSP chip power supply rise time. Switching three series connected 1.2 Ah NiCd cells with a total internal resistance of 30 m Ω into 200 μF of decoupling capacitance gives a maximum dV/dt of approximately 1 V/ μs . In practice, wiring inductance and the resistance of protective fuses limit dV/dt to <0.1 V/ μs .

$$C_{\text{IN}}|_{\text{MAX}} = I_{\text{IN}}|_{\text{MAX}} * \frac{dV_{\text{DD}}}{dt}|_{\text{MAX}}$$

Therefore, C_{IN} should not greatly exceed 1 nF.

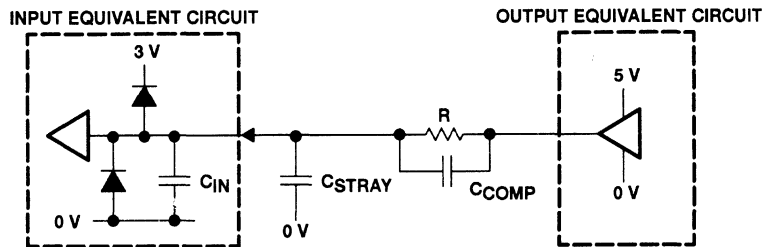


Figure 11. Interfacing to 3-V DSP – Component Values

4.4 Programming

4.4.1 Initialization

Only those registers that have to be changed from their defaults need to be reprogrammed. The initialization process consists of sending pairs of data values from the 16-bit synchronous serial interface of the DSP chip to the TLC320AC01. In most cases the first word of the pair will be 0000 0000 0000 0011B. The 14 most significant bits of this value (bits 15 to 2) specify that an output sample of zero be sent and the two least significant bits (bits 1 and 0) specify that the next word transmitted will be interpreted as a secondary communication.

The secondary data value is used to reprogram one of the nine registers. Bits 15 and 14, which control phase shifting in modem applications will usually be zero, bit 13 = 0 specifies that data is to be written to a register, bits 12 to 8 define the address of the register that is to be changed. Bits 7 to 0 contain the data to be stored in the register.

4.5 Register Descriptions

4.5.1 Pseudo Register 0 (no-op)

The main purpose of R0 is to allow phase shift commands to be sent as secondary communications without reprogramming any other register. It is not needed for most applications.

4.5.2 Register 1 (A Register)

The A register sets half the number by which the master clock input (MCLK) is divided to provide the switched capacitor filter clock (FCLK). This is also the principal method for setting the sampling frequency.

4.5.3 Register 2 (B Register)

The B register sets the ratio between the low-pass filter corner frequency and the sampling frequency. For most purposes the default, or a value close to it will be appropriate.

4.5.4 Register 3 (A' Register)

The A' register is used for phase shift control and can be ignored for most purposes.

4.5.5 Register 4 (Amplifier Gain Select Register)

This allows the gains of the analog input and output to be varied by -6 dB or -12 dB or disabled. The monitor output can be varied by -8 dB or -18 dB or disabled.

4.5.6 Register 5 (Analog Configuration Register)

This selects whether the high-pass filter is to be disabled, thus allowing the codec to respond to dc, and controls the input multiplexer.

4.5.7 Register 6 (Digital Configuration Register)

Control operating modes and power-down options. The defaults will be suitable for many applications.

4.5.8 Register 7 (Frame-Sync Delay Register)

This controls the timing of the serial data transmission of a slave converter in multi-channel multiplexed systems.

4.5.9 Register 8 (Frame-Sync Number Register)

This controls the number of frame-sync pulses generated, corresponding to the number of channels being multiplexed on to the bused serial interface. The default of 1 is suitable for single channel operation.

4.6 TLC320AC01/TMS320C50 Demonstration Program

The demonstration program AC01DEMO.ASM carries out the simplest possible operation, reading in a sample from the ADC in the TLC320AC01 and then writing it to the DAC. It is assembled and linked using the commands in the batch file MAKE.BAT. This is called as follows: MAKE AC01DEMO.

The program begins with the definition of some variables and allocation of their memory locations. The COFF assembler used here does not assign absolute addresses, but instead relative positions within named blocks of memory. The linker then resolves these references in conjunction with information stored in the linker command file AC01DEMO.CMD.

The next section of the program is the definition of macros that will be used later. Using macros makes the main program listing easier to understand by hiding some of the frequently repeated details.

The section called vectors is loaded into flash EPROM at address zero, which is where the TMS320C50 starts executing after reset. The .text section is the main body of the program, and would typically be loaded into the memory section flashp defined in the command file. In this example, however, it has been placed immediately after the vectors section in the protected bootstrap area for convenience of testing.

The main program starts by initializing certain processor registers that are undefined or have unsuitable defaults at start-up, then clearing the memory variables. The code which is to run in real-time is copied from flash EPROM to the on-chip single-access RAM block for maximum speed of execution. The serial port is initialized to use external clock and frame synchronization pulses, and to transfer 16-bit data words. The initial behavior of the serial port is unpredictable when it is reset with the frame sync input high, as is the case when the TLC320AC01 is inactive. Therefore, a dummy value of zero is sent, and afterwards the TLC320AC01 is again reset briefly. Now the interface is properly initialized and the program branches to the real-time processing loop.

The processor waits in a low power idle mode until an interrupt is received. Then it determines whether the interrupt was from the serial port, in which case it executes the processing loop. The processed results from the previous sample are written to the serial port data transmit register, then the fresh ADC data is read in from the data receive register and processed. The results are stored ready to be sent to the DAC on the next interrupt. This double buffering method maximizes the processing time available because processing can take place while serial data is being transmitted and received. The two least significant bits of the output data are masked out to ensure that a secondary communication request is not inadvertently sent.

The serial port receive interrupt routine simply sets a flag to indicate that data is available. There is no need to have a separate transmit interrupt because the transmit and receive operations are inherently synchronous with each other.

4.7 TMS320C50 Assembler Listing

```
.title "AC01 demonstration program"
.width 200
.version 50          ; Makes assembler generate C50 code
.mmregs             ; Predefine names for memory mapped registers

; This program initializes the 'C50 processor and serial port, then initializes the '
; 'AC01 codec and starts the main signal processing loop. In this example, a data
; sample is read from the adc and written back to the dac unchanged.

; Using rev 6.40 or higher assembler tools, use the following make file

; @echo off
; if "%1" == "" goto :nofile
; dspa %1.asm -x -w -s -v50 -l
; if not errorlevel 1 dsplnk %1.obj -o %1.out -m %1.map %1.cmd
' gpt "dpme
; :nofile
; echo no source file!
; :done

; -s option makes all symbols global, and thus accessible to the emulator and
; simulator.
; -w option warns about pipeline conflicts.
; -x option makes a cross reference table.
; -l option generates listing file

; If an eprom programmer is used it may also be necessary to use the DSPHEX conversion
; program to split the linker output file which is in COFF format into a pair of high
; and low byte files in HEX format.

FSAMP      .set 16          ; 8 seslects 8 kHz, 16 selects 16 kHz

; The following 2 variables must be in memory block b2 and dp set to 0 because they
; are accessed by direct addressing

gotdataflag .usect      "b2", 1 ; used to signal that an interrupt came from the
                                ; serial input port
outputbuffer .usect    "b2", 1 ; temporarily store output sample

; Macro definitions

waitint .macro
waitint?
    lacc  gotdataflag
    bz   waitint?      ; wait for semaphore to be changed
    splk #0, gotdataflag ; set it again
    .endm

progreg .macro progval
    splk #11b, dxr      ; request secondary comms
    waitint              ; wait for transmission
    splk #:progval:, dxr ; send value
    waiting              ; wait . . . .
    .endm

    .sect "vectors"      ; vectors is the starting point of a block of program
                        ; memory starting at address zero

Interrupt vectors - these start at address zero
; unused interrupts branch to themselves so that if they are inadvertently activated
; they can be identified using the xds510 emulator
rs      b mainentry
int1    b int1
int2    b int2
int3    b int3
tint    b tint
rint    b getdata
xint    b xint
trnt    b trnt
txnt    b txnt
int4    b int4
rsvd14  b rsvd14
rsvd16  b rsvd16
rsvd18  b rsvd18
rsvd1A  b rsvd1A
rsvd1C  b rsvd1C
```

```

rsvd1E b rsvd1E
rsvd20 b rsvd20
trap b trap
nmi b nmi
rsvd26 b rsvd26
rsvd28 b rsvd28

        .text        ; .text indicates start of main program storage block in flash eprom
mainentry        ; this is the startu entry point
    ldp #0        ; data page pointer to page zero
    setc INTM    ; globally disable interrupts
    setc SXM     ; set sign extension mode
    setc OVM     ; set saturation on arithmetic overflow

; Disable address visibility (to save power by not driving address bus)
; set up on-chip single access ram and B0 to be in data space for initialization.
    splk #000000010101000b, PMST
    circ CNF     ; B0 is in data space

; Set up wait state control registers for 2 wait states when accessing flash eprom
    splk #00000b, CWSR
    splk #1010101010101010, PDWSR

    splk #0, gotdataflag ; zero data received flag
    splk #0, outputbuffer ; zero output storage buffer

; relocate speed critical part of program to on chip ram
    lrlk AR1, 800h        ; address in data memory of start of ram block
    larp AR1
    lacc #ocramstart     ; address in flash memory of start of code
    rpt #ocramend-ocramstart-1
    tblr ++

    apl #11111111101111b, PMST ; remove ram from data space
    opl #000000000100000b, PMST ; put it in program space

; set all interrupt masks except serial receive
    splk #000010000b, IMR

; set up serial port
    splk #0, dxr        ; zero the data transmit register
    splk #0001000b, SPC ; use ext clock and frame sync
    opl #0c0h, SPC     ; take it out of reset

; clear all interrupt flag bits
    splk #0ffffh, IFR
    clrc intm          ; enable interrupts

    clrc xf           ; release codec from reset
waitint          ; wait for interrupt from serial port

; this code assumes that XF is inverted in hardware
; reset the codec and release it again to make it ignore first garbage word
; generated by serial port in revision 1 'C50 silicon
    setc xf
    rpt #10           ; hold 'AC01 reset low for at least 1 MCLK period
    nop              ; ie > 100 ns for MCLK = 10 MHz
    clrc xf

; serial interface and 'AC01 are now in a stable state
; setup codec - only need to reprogram those registers that need to be changed from
; their defaults
                                ; reg 0 = no op
                                ; reg 1 = A register (18 = default)
    .if FSAMP = 8
        progreg 0000000101000101b ; 36 -> 8 kHz @10.368 MHz clockin
    ;endif                          ; 35 -> 7.937 kHz @10 MHz

    .if FSAMP = 16
        progreg 0000000100100010b ; 18 -> 16 kHz @10.368 MHz clockin
    ;endif                          ; 17 -> 16.34 kHz @10 MHz

```



```

getdata   splk   #1, gotdataflag ; set a flag to indicate data available
rete     ; return from interrupt, restoring context and re-enabling interrupts

        .label ocramend ; end of block transferred to on-chip ram
.end

```

4.8 Linker Command File: AC01DEMO.CMD Listing

```

MEMORY          /* memory map for C50 */
{
page 0 :/* program memory */
reset   : origin = 0, length = 800h /* booth block up to start of on chip ram +/
onchipp : origin = 800h, length = 2400h /* on chip program memory*/

flashp : origin = 8000h, length = 7200h /* top half flash prog except b0 */
param2  : origin = 3000h, length = 1000h /* second parameter block in eprom */
        /* par. block is overlaid by on-chip ram */

page 1 : /* data memory */
b3      : origin = 60 h, length = 20h
b0b1    : origin = 800h, length = 240h /* ocram is on-chip data if OVLY=1 */
        /* external flash eprom if OVLY=0 */
}

SECTIONS
{
vectors : load = reset page 0
.text   : load = flashp page 0
param2  : load = param2 page 0
ocram   : load = flashp page 0 run = onchipp page 0

be      : load = b2 page 1 /* data page 0 on-chip ram */
.bss    : load = b0b1 page 1
}

```

4.9 Measuring the DAC Filter Response with a White Noise Generator

A convenient way of measuring the frequency response of a linear system is to excite it with white noise and measure the response with a spectrum analyzer. This example shows how white noise can be generated by a very short random bit generator program and used to measure the response of the TLC320AC01's DAC reconstruction filter.

The random bit generator implements a recurrence relation in a primitive polynomial modulo 2 of order 31 (reference 1). This gives a maximal length sequence of pseudo-random bits which only repeats after $2^{31} - 1$ iterations. The polynomial used is $x^{31} + x^3 + x^0$, although there are many others to choose from. A 32-bit variable, noise_sr, which is initially seeded with any non zero value, stores the state between iterations. On each iteration, the accumulator is loaded from noise_sr and shifted left one bit. The most significant bit (now in the carry bit) is then exclusive ORed (XOR) with the remaining non zero terms. Each bit that has been XORed is stored back into the same location in the accumulator and the result is saved. This is implemented by testing the carry bit after the shift with the execute conditional (XC) instruction. If C was 0, do nothing because anything XORed with 0 is 0 and bit zero of the accumulator is filled with a 0 after a shift. If C was 1, XOR the low accumulator with the constant 10010b which achieves the desired result.

There are three main limitations to this technique. Because the XOR is only carried out on the 16 least significant bits there must not be any non zero terms in the polynomial above x^{15} apart from x^{31} . The contents of the accumulator should not be used directly as a random number because successive values are correlated as the bits work their way to the left. This is overcome in the example by iterating the code 14 times for each sample. Although the noise has a white long-term spectrum (that is equal power per unit frequency), it is nongaussian. This does not matter for frequency response measurements.

Figure 12 shows the response of the TLC320AC01 reconstruction filter measured at a sampling rate of 7.937 kHz. The A register value is 42, the B register value is 15 and the MCLK frequency is 10 MHz.

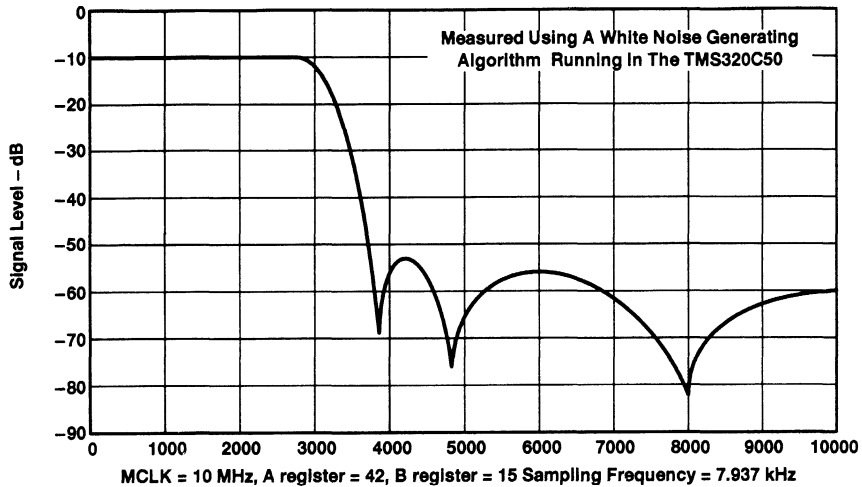


Figure 12. DAC Channel Frequency Response

4.10 Example Noise Generator Code Listing

```

noise_sr      .usect "b2", 2      ; allocate 32 bits of data memory
; . . .
    larp      AR1      ; seed random bit generator with 2
    lrlk     AR1, noise_sr
    lac      #2
    sac1     **
    zac
    sac1     *
; . . .
; execute this section once per dac output sample
    larp      AR1
    lrlk     AR1, noise_sr
    lacl     **          ; load low accumulator from data memory
    add     *, 16       ; load high accumulator
    splk     #13, brcr   ; repeat block 14 times to decorrelate sequential bits
    rptb    end_noise - 1
    sfl
    nop
    xc      1, C        ; execute next instruction if carry set
    xor     #10010b     ; xor bit 3 with bit 31, copy bit 31 to bit 0
end_noise

    sach     *-          ; save high accumulator to data memory
    sac1     *          ; save low accumulator

; Write low accumulator to transmit data register (after masking out bottom 2 bits)

```

5 SAMPLING AND QUANTIZATION – TUTORIAL

5.1 Sampling

5.1.1 Ideal Sampling

In converting a continuous time signal into a discrete digital representation, the process of sampling is a fundamental requirement. In an ideal case, the sampling signal is a train of impulses (infinitesimally narrow with unit area). The frequency of these impulses is the sampling rate (f_s). The input signal can also be idealized by considering it to be truly band limited, containing no components in its spectrum above a certain frequency.

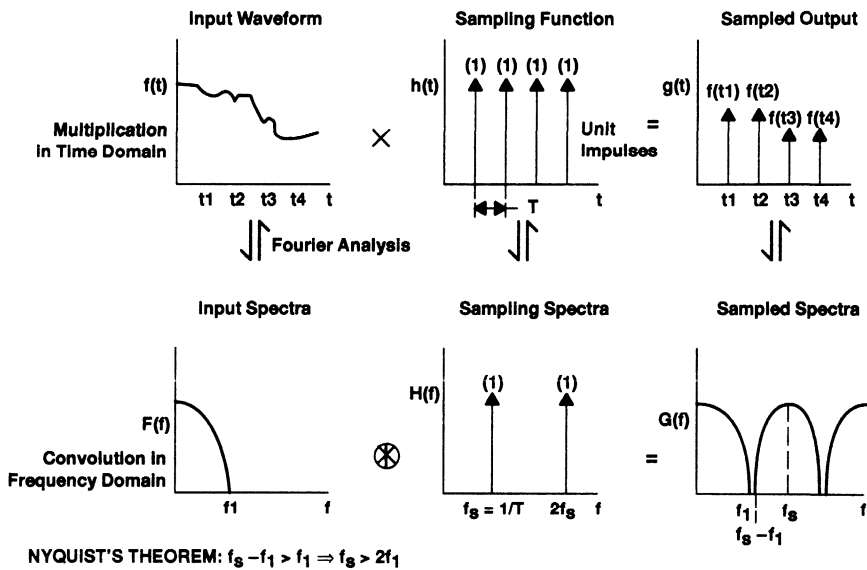


Figure 13. Ideal Sampling

The ideal sampling condition is shown in Figure 13, represented in both the frequency and time domains. The effect of sampling in the time domain is to produce an amplitude modulated train of impulses representing the value of the input signal at the instant of sampling. In the frequency domain, the spectrum of the pulse train is a series of discrete frequencies at multiples of the sampling rate. Sampling convolves the spectrum of the input signal with that of the pulse train to produce the combined spectrum shown, with double sidebands around each discrete frequency which are produced by the amplitude modulation. In effect, some of the higher frequencies are folded back so that they produce interference at lower ones. This interference causes distortion which is called aliasing. Aliases cannot be removed by subsequent processing.

As shown in the diagram, if the input signal is band limited to a frequency f_1 and is sampled at frequency f_s , the overlap (and hence aliasing) cannot occur if

$$f_1 < f_s - f_1 \text{ or } 2f_1 < f_s$$

Therefore, if sampling is performed at a frequency at least twice as great as the maximum frequency of the input signal, no aliasing occurs and all of the signal information can be extracted. This is *Nyquist's Sampling Theorem*, and it provides a basic criterion for the selection of the sampling rate required by the converter to process an input signal of a given bandwidth.

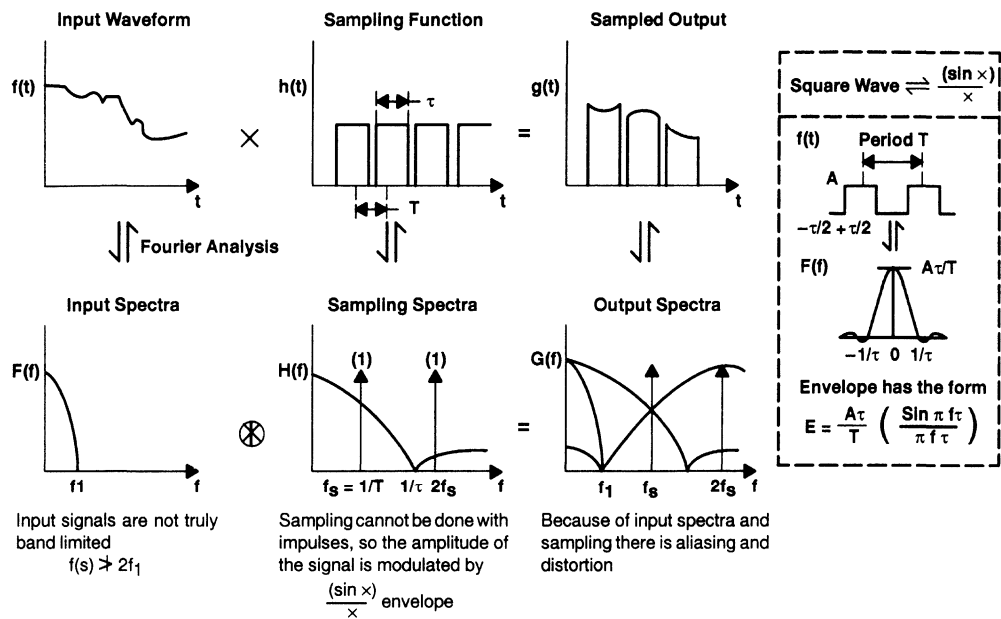


Figure 14. Real Sampling

5.1.2 Real Sampling

The concept of an impulse is a useful one to simplify the analysis of sampling. However, it is a theoretical ideal which can be approached but never reached in practice. Instead the real signal is a series of pulses with a period equalling the reciprocal of the sampling frequency. The result of sampling with this pulse train is a series of amplitude modulated pulses.

Examining the spectrum of a square wave pulse train shows a series of discrete frequencies, as with the impulse train, but the amplitude of these frequencies is modified by an envelope which is defined by $(\sin x)/x$ (sometimes written $\text{sinc}(x)$) where x in this case is $\pi f_s \tau$. For a square wave of amplitude A , the envelope of the spectrum is defined as

$$\text{Envelope} = A \left(\frac{\tau}{T} \right) \left[\frac{\sin(\pi f_s \tau)}{\pi f_s \tau} \right]$$

The error resulting from this can be controlled with a filter which compensates for the sinc envelope. This can be implemented as a digital filter, in a DSP, or using conventional analog techniques. (The TLC320AC01 analog interface circuit has an on-chip $(\sin x)/x$ correction filter after its DAC output for this purpose.)

5.1.3 Aliasing Effects and Considerations

In practice, any real signal has infinite bandwidth. However, the energy of the higher frequency components become increasingly smaller so that at a certain value they can be considered to be irrelevant. This value is a choice that must be made by the system designer.

As shown, the amount of aliasing is affected by the sampling frequency and by the relevant bandwidth of the input signal, filtered as required. The factor that determines how much aliasing can be tolerated is ultimately the resolution of the system. If the system has low resolution, the noise floor is already relatively high and aliasing can have an insignificant effect. However, with a high resolution system, aliasing can increase the noise floor considerably and therefore needs to be controlled.

As shown, increasing the sampling rate is one way to prevent aliasing. However, there is a limit on what frequency this can be, determined by the type of converter used and also by the maximum clock rate of the digital processor receiving and transmitting the data. Therefore, to reduce the effects of aliasing to within acceptable levels, analog filters must be used to alter the input signal spectrum.

5.2 Theoretical SNR for a 14-Bit Device

The analog input to an ADC is a continuous signal with an infinite number of possible states, whereas the digital output is by its nature a discrete function with a number of different states determined by the resolution of the device. It follows from this therefore, that in converting from one form to the other, certain parts of the analog signal that were represented by a different voltage on the input, are represented by the same digital code at the output. Some information has been lost and distortion has been introduced into the signal. This is quantization noise.

For an ideal staircase transfer function of an ADC, the error between the actual input and its digital form has a uniform probability density function if the input signal is assumed to be random. It can vary in the range of $\pm 1/2$ least significant bit (LSB) or $\pm q/2$ where q is the width of one step.

$$p(\epsilon) = 1/q \text{ for } -q/2 \leq \epsilon \leq +q/2$$

$$p(\epsilon) = 0 \text{ otherwise}$$

The average noise power (mean square) of the error over a step is given by

$$E^2(\epsilon) = \frac{1}{q} \int_{-q/2}^{+q/2} \epsilon^2 d\epsilon$$

which gives $E^2(\epsilon) = q^2/12$

The total mean square error, N^2 , over the whole conversion area is the sum of each quantization level's mean square multiplied by its associated probability. Assuming the converter is ideal, the width of each code step is identical and therefore has an equal probability. Hence for the ideal case

$$N^2 = \frac{q^2}{12}$$

Considering a sine wave input $F(t)$ of amplitude A so that

$$F(t) = A \sin \omega t$$

which has a mean square value of $F^2(t)$, where

$$F^2(t) = \frac{1}{2\pi} \int_0^{2\pi} A^2 \sin^2(\omega t) dt$$

which is the signal power. Therefore the signal-to-noise ratio (SNR) is given by

$$\text{SNR(dB)} = 10 \text{ Log} \left[\left(\frac{A^2}{2} \right) / \left(\frac{q^2}{12} \right) \right]$$

But $q = 1 \text{ LSB} = 2A/2^n = A/2^{n-1}$

Substituting for q gives

$$\text{SNR} = 10 \text{ Log} \left[\left(\frac{A^2}{2} \right) / \left(\frac{A^2}{3 \times 2^{2n}} \right) \right] = 10 \text{ Log} \left(\frac{3 \times 2^{2n}}{2} \right)$$

$$\Rightarrow 6.02n + 1.76 \text{ dB}$$

This gives the ideal value for a perfect n -bit converter and shows that each extra bit of resolution provides approximately 6 dB improvement in the SNR. In practice, errors in the ADC introduce non-linearities that lead to a reduction of this value.

For a perfect 14-bit converter, the SNR is:

$$6.02 \times 14 + 1.76 \approx 86 \text{ dB}$$

5.3 References

1. William H. Press, Brian P. Flannery, Saul A. Teukolsky and William T. Vetterling, 1988, Numerical Recipes in C – The Art of Scientific Computing, (Cambridge: Cambridge University Press) pp 224–228.
2. TLC320AC01 Analog Interface Circuit Data Manual; SLAS057A
3. TMS320C2x User's Guide; SPRU014C
4. TMS320C5x User's Guide; SPRU056B
5. TMS320 Fixed-Point DSP Assembly Language Tools; SPRU018C

***Interfacing the TLV1549
10-Bit Serial-Out ADC to
Popular 3.3-V Microcontrollers***

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INTRODUCTION

The TLV1549 is a 10-bit serial out analog-to-digital converter that operates from a 3.3-V (± 0.3 V) single supply. It uses a switched-capacitor successive-approximation method to perform the conversion in a maximum of 21 μ s.

This application report describes how to interface the TLV1549 to three popular microcontrollers which operate from a single 3.3-V supply rail. These are the 68HC05, the TMS70C02, and the 80C51-L.

Interface Timing

The timing for each of the interfaces described in this application report is illustrated in Figure 1. One chip-select (\overline{CS}) pulse is used for each 10-bit conversion and 16 CLOCK I/O pulses are between each \overline{CS} .

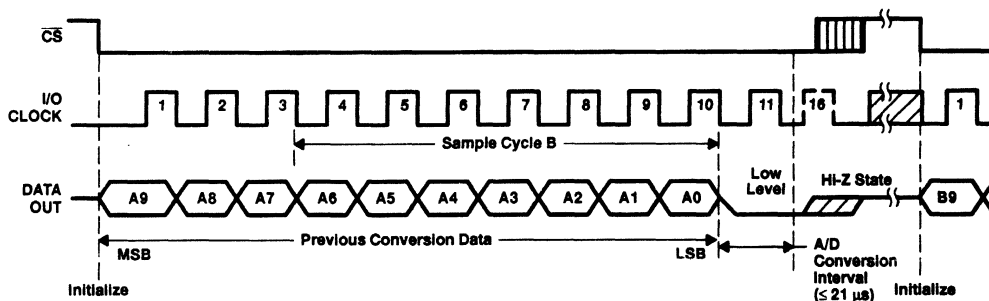


Figure 1. Timing for the 11- to 16-Clock Transfer Using \overline{CS} (Serial Transfer Completed After 21 μ s)

Use of Software Subroutines

The subroutines included in this application report have been developed as much as possible as relocatable pieces of software. They include a provision for setting the number of consecutive conversions to be performed. This is either set in the main program as in the TMS7000 and 80C51-L examples or inside the subroutine as used in the 68HC05 example, by programming the number of conversions into COUNT. It is recommended that at least two conversions are performed either after a power-up reset or after a protracted interval between the last conversion. This enables the TLV1549 on-board sample-and-hold to acquire the most recent signal level during the first conversion cycle before converting it into digital form during the second cycle.

Data Format

In whatever format the data arrives at the microcontroller, it is important to ensure that any reformatting, if required, puts the data into a convenient final format. This application report places the most significant byte of the conversion result in one byte of random access memory (RAM) and the least significant byte in an adjacent byte of RAM. The two least significant bits of the 10-bit result are placed in the least significant bit locations of their RAM location.

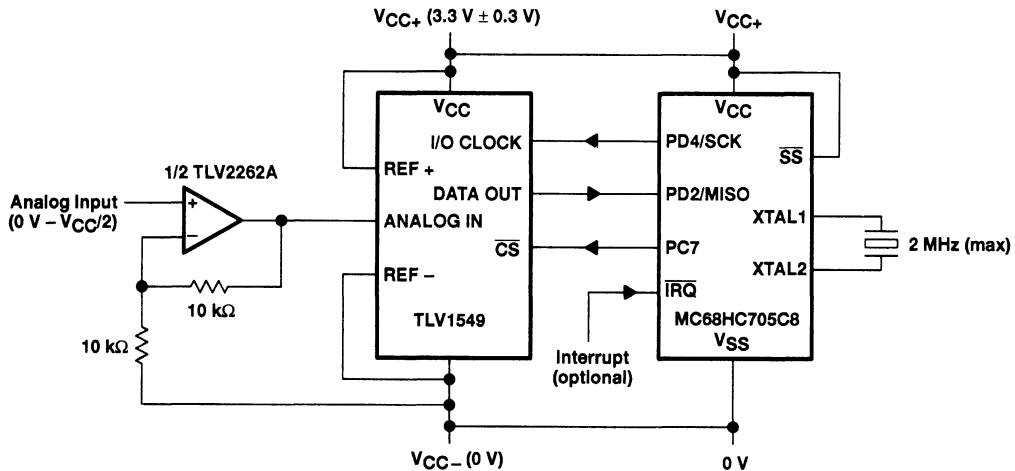
This format gives the user the flexibility to use only 8-bit precision data, if so required, to add the MS and LS bytes together for use in 16 bit wide architectures, to view the two least significant bits of the result for fine tuning applications, or to reformat into another more convenient format.

TLV1549-TO-68HC05 INTERFACE

Microcontroller Features

The M68HC05 family of microcontrollers consists of several different product variants of the basic architecture. It is important that the correct product type is specified to ensure that it contains all the features and attributes necessary to fulfill all its eventual system requirements.

In the case of its suitability for interfacing to the TLV1549 serial out ADC, the M68HC05 product type should contain a serial peripheral interface (SPI). Several types contain this feature including the MC68HC705C8, which was chosen as the target for this ADC interface.



NOTE: For 68HC05 operating off 3.3 V dc supply:

Maximum I/O clock frequency = maximum crystal clock frequency/4 = 0.5 MHz

Figure 2. TLV1549 10-Bit Serial Out ADC-to-MC68HC705C8 Microcontroller Interface

Interface Circuit

Figure 2 shows the circuit interconnections for the TLV1549–MC68HC705C8 microcontroller interface. No glue logic is required. The positive reference to the TLV1549 is provided directly from the V_{CC+} supply. The analog signal is scaled by an appropriate factor (a gain of two in this case) and buffered by one half of a TLV2262A dual operational amplifier.

The three digital interface terminals, I/O CLOCK, DATA OUT, and \overline{CS} of the TLV1549 connect directly to the PD4/SCK, PD2/MISO, and PC7 terminals respectively of the microcontroller. When the SPI is enabled, PD4 becomes SCK, which is the serial clock output, and PD2 becomes the master in slave out (MISO) terminal. When programmed to be a master device, the microcontroller receives serial data at its MISO terminal.

Figure 3 shows the shift register operation of the SPI when connected to a serial output peripheral component such as the TLV1549. The MC68HC705C8 operates as the master device and the TLV1549 acts as the slave.

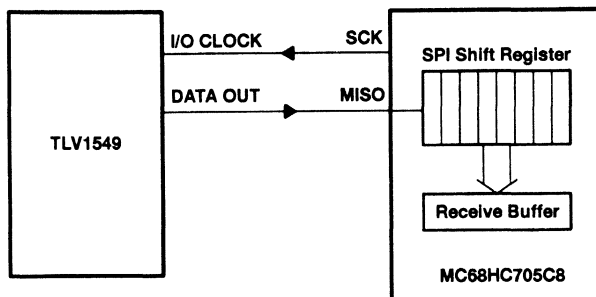


Figure 3. Shift Register Operation of the Serial Peripheral Interface (SPI)

Software Considerations

The three registers which are used for SPI communications are:

- Serial peripheral control register (SPCR)
- Serial peripheral status register (SPSR)
- Serial peripheral data I/O register (SPDR)

Serial Peripheral Control Register (SPCR)

Bits 0 and 1 of the SPCR program the SPI master bit rate. With bits 0 and 1 set to 0, SCK runs at the internal processor clock/2. This means that SCK operates at one quarter of the microcontroller XTAL frequency.

Bit 2 determines the phase relationship between the clock transmitted at SCK and the data appearing on the MISO terminal. If a 0 is placed in bit 3, SCK idles low. This is the correct condition for the TLV1549. A 1 in bit 6 of the SPCR enables the SPI. A 0 in bit 6 disables the SPI. A 1 in bit 4 (MSTR) confers the status of master to the microcontroller.

Serial Peripheral Status Register (SPSR)

The most important bit of the SPSR is bit 7 (SPIF). When set to 1, it indicates that a data transfer between the TLV1549 and the microcontroller has been completed. The SPIF bit is automatically cleared when the SPSR is read and the SPI data register is accessed.

Serial Peripheral Data I/O Register (SPDR)

When the SPIF bit of the SPSR is 1, the SPDR contains the received byte of information from the converter. The contents of SPDR can then be read into a suitable register or location.

Program Listing

The program listing for the TLV1549-to-MC68HC705 interface shown in Figure 2 is included in the following section. COUNT has been set to 2; this ensures that two conversions are performed each time the ADC subroutine is used. The first conversion flushes out potentially erroneous data from the converter output registers. For test purposes, the main program simply performs continuous repeat jumps to the ADC subroutine.

The SPI expects the most significant bit of each received byte to arrive first which is compatible with the order of the TLV1549 output bit stream. This means that no reformatting of the most significant bit of the 10-bit conversion result is required. However, the least significant byte does need to be shifted right by 6 bits.

Program Listing for the TLV1549-to-MC68HC705 Interface

```

1      * * * * *
2      *
3      *           TLV1549 - MC68HC705C8 Interface Program
4      *
5      *   This program contains a subroutine ADC which reads
6      *   the serial data from two conversions of the TLV1549
7      *   and places the MSByte in address 50H and the LSByte
8      *   in address 51H.
9      *   The data from the first conversion(potentially
10     *   erroneous) is overwritten by the result from the
11     *   second conversion.
12     *
13     * * * * *
14 000A   SPCR      EQU 0AH      * * * * *
15 000B   SPSR      EQU 0BH      * * * * *
16 000C   SPDR      EQU 0CH      * * * * *
17 0002   PORTC     EQU 02H      * Names, Peripheral, and
18 0006   DDRC      EQU 06H      * Control Registers
19 0011   SCDAT     EQU 11H      *
20 000E   SCCR1     EQU 0EH      *
21 000F   SCCR2     EQU 0FH      *
22 0010   SCSR      EQU 10H      * * * * *
23 0050   MSBYTE    EQU 50H      * * * * *
24 0051   LSBYTE    EQU 51H      * Names working RAM addresses
25 1FFE   RESETH    EQU 1FFEH    *
26 1FFF   RESETL    EQU 1FFFH    *
27 0052   COUNT     EQU 52H      * * * * *
28 0160   ORG 160H   Start Program at 160H
29 0160   A601      LDA #01H
30 0162   C71FFE    STA RESETH    Load Reset Vector High Byte
31 0165   A660      LDA #60H
32 0167   C71FFF    STA RESETL    Load Reset Vector Low Byte
33 016A   CD016F    START      JSR ADC
34 016D   20FB     BRA START
35 016F   1E06     ADC         BSET 7, DDRC
36 0171   A602      LDA #02H
37 0173   B752     STA COUNT
38 0175   A610     CONVERT     LDA #10H
39 0177   1E02     CSHIGH     BSET 7, PORTC    Set Port C bit 7 (TLV1549 CS) high
40 0179   4A       DECA
41 017A   26FB     BNE CSHIGH
42 017C   1F02     BCLR 7, PORTC  Reset TLV1549 CS (Low)
43 017E   A650     LDA #50H      Load accumulator with 50H
44 0180   B70A     STA SPCR      Load SPI control register
45 0182   A600     LDA #00H      Load dummy data into accumulator
46 0184   B70C     STA SPDR      Receive SPI data
47 0186   0F0BFD   HBYTE     BRCLR 7, SPSR, HBYTE
48 0189   B60C     LDA SPDR
49 018B   B750     STA MSBYTE    Put MSBYTE in Location 50
50 018D   A600     LDA #00H      Load dummy data into accumulator
51 018F   B70C     STA SPDR      Receive SPI data
52 0191   0F00FD   LBYTE     BRCLR 7, 0B, LBYTE
53 0194   B60C     LDA SPDR
54 0196   B751     STA LSBYTE    Put LSBYTE in Location 51
55 0198   3A52     DEC COUNT
56 019A   B652     LDA COUNT
57 019C   26D7     BNE CONVERT    If COUNT = 1, do another conversion
58 019E   A606     LDA #06H
59 01A0   98       FORMAT     CLC
60 01A1   3651     ROR LSBYTE    Reformats LSBYTE
61 01A3   4A       DECA
62 01A4   26FA     BNE FORMAT
63 01A6   81       RTS
64 01A7   END

```

TLV1549-TO-TMS7000 INTERFACE

Microcontroller Features

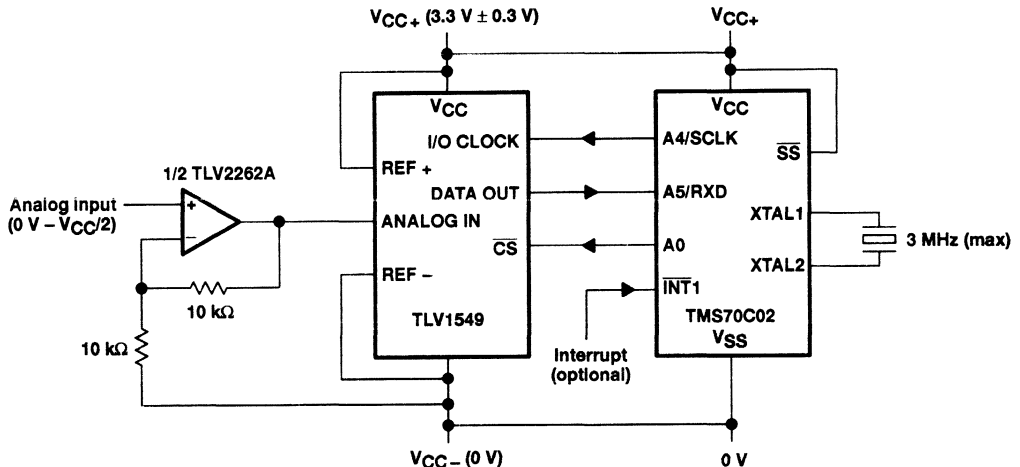
The entire range of TMS7000 microcontrollers can be operated with a 3-V supply. However, the maximum crystal frequency they will tolerate at this supply voltage (over the full temperature range) is 3 MHz. The inherently longer instruction cycle times that this yields should be taken into account when deciding how many software delay loops are necessary to produce the required delay.

Within the family of TMS7000 microcontrollers, three types are available that have a serial port: TMS70Cx2, TMS77C82, and TMS70Cx8. This application report refers to the TMS70Cx2, but any one of these three types could be chosen to efficiently implement a serial interface to the TLV1549.

Three modes of serial communication are available for the serial port: asynchronous mode, isosynchronous mode, and the serial I/O mode. The most suitable of these for interfacing the TMS70Cx2 to the TLV1549 is the serial I/O mode.

Interface Circuit

The TLV1549-to-TMS70C02 interface circuit is shown in Figure 4. The chip select (\overline{CS}) of the TLV1549 is controlled by the output from A0 (bit 0 of peripheral port A).



NOTE: Maximum I/O clock frequency = microcontroller crystal frequency/8

Figure 4. TLV1549 10-Bit Serial Out ADC-to-TMS70C02 Microcontroller Interface

Serial I/O Mode

Four peripheral registers are used to set up and control the serial I/O mode of the microcontroller:

- Serial mode register (SMODE)
- Serial control register 0 (SCTL0)
- Serial control register 1 (SCTL1)
- Serial port status register (SSTAT)

The contents of the SMODE register determine the data format and type of communication mode (serial I/O for example). In the serial I/O mode, the frame format of each character is five to eight data bits followed by a stop bit. Setting the number of bits to eight can simplify the software necessary to implement the interface.

SCTL0 enables either transmit or receive communication. SCTL1 determines the source of SCLK and programs the frequency of SCLK.

SSTAT is a read-only register that is used for checking the status of the serial port. Bit 1 (RXRDY) of SSTAT is 0 when the receive buffer (RXBUF) is empty and 1 when RXBUF is full.

Provision of TLV1549 Chip Select (\overline{CS})

On power-up and/or system reset, the TLV1549 chip-select terminal (\overline{CS}) should be initialized to a high level. To provide this, one of the bidirectional peripheral port bits can be programmed as an output and set to a 1 for a period of at least 21 μ s. This period is provided by a delay loop at the beginning of the ADC subroutine. The number of times the loop is executed in order to achieve at least 21 μ s is dependent on the clock frequency of the microcontroller and the number of instruction cycles contained within the delay loop. The example program listing shown in the section program listing for TLV1549-to-TMS70C02 microcontroller interface executes the loop 16 times, but the loop can be executed less times to optimize the conversion throughput rate.

On completion of this delay loop, the particular peripheral port bit is reset to 0, and the converter is now ready to send out data from the previously performed conversion.

Data Reformatting and Storage

After RXBUF is checked to verify it is full, its contents can be read to a suitable register for subsequent access and processing. In the case of the 10-bit conversion result from the TLV1549, two successive bytes of data are received and each are placed in RXBUF to be read consecutively into two convenient memory locations.

The TLV1549 sends the digital result of each conversion with the most significant bit first and the least significant bit last. This is the reverse of the order that the TMS70C02 expects. A few software instructions are therefore inserted near the end of the conversion subroutine that reformat the data into the correct order for interpretation by the microcontroller.

Other Software Considerations

The subroutine that services the TLV1549 conversion should be located in a convenient area of memory that is compatible with the rest of the system. For example, all serial port versions of the TMS7000 family have 8K bytes of EPROM. This EPROM is located between addresses E000H (hex) and FFFFH. A converter subroutine start address at the midpoint of this EPROM memory space may be convenient in that it leaves the first half of this space for the location of the main program. The example program listing in the section Program Listing for TLV1549-to-TMS70C02 Microcontroller Interface uses a start location of F006 which is convenient for the emulation system it was developed on.

On system reset, the stack pointer is at location 0001H. In programs that include nested subroutines where the number of RAM locations taken up by the stack becomes large, the stack can interfere with other useful or even critical RAM locations. It is therefore prudent to reposition the stack pointer, immediately after reset, at a higher address in RAM such as 0060H. This allows the stack plenty of room to grow and avoids interference with lower address RAM locations.

Software Listing

The following program listing reads in the results of two 10-bit conversions from the TLV1549. The software routine ADC actually reads in the results from N conversions, where N is the contents of the register COUNT. The first conversion in a sequence of conversions may be erroneous because the data received is derived from a previous (probably invalid) sample of the analog signal. It is often useful to flush out this first spurious reading before receiving a second valid conversion result. The setting of the contents of COUNT is performed within the main program and should normally be set to a minimum of two.

Program Listing for TLV1549-to-TMS70C02 Microcontroller Interface

```

0001      * * * * *
0002      *           TLV1549 - TMS70C02 Interface Program
0003      *
0004      *   This program contains a subroutine ADC which reads in
0005      *   the serial data from two conversions of the TLV1549. The
0006      *   data (potentially erroneous) from the first conversion
0007      *   is overwritten by the data from the second conversion.
0008      *   The most significant byte is placed in register 16. The
0009      *   least significant byte is placed in register 17.
0010      * * * * *
0011      0004  APORT  EQU P4      * * * * *
0012      0005  ADDR   EQU P5      *
0013      0014  SMODE  EQU P20     *
0014      0015  SCTL0  EQU P21     *
0015      0016  SSTAT  EQU P22     *   Name Peripheral Registers
0016      0018  SCTL1  EQU P24     *
0017      0019  RXBUF  EQU P25     *
0018      001A  TXBUF  EQU P26     *
0019      0009  COUNT  EQU R9      *   Name Count and Result Registers
0020      0010  MSBYTE EQU R16     *
0021      0011  LSBYTE EQU R17     * * * * *
0022      F006      AORG >F006     Set start address of program
0023      F006  52  START  MOV  %>60,B  Set stack register
0024      F007      60
0025      F008  0D          LDSP
0025      F009  A2          MOVP %>11,ADDR  Set up Port A Data Direction Register
0026      F00A      11
0026      F00B      05
0026      F00C  A2          MOVP %>0C,SMODE Set up Serial Mode Register
0026      F00D      0C
0026      F00E      14
0027      F00F  72          MOV  %>02,COUNT  Set COUNT = 2
0027      F010      02
0027      F011      09
0028      F012  8E          CALL @ADC      Call Subroutine ADC
0028      F013  F017
0029      F015  E0          JMP  START      On return from Subroutine ADC, jump to START
0029      F016  EF
0030      F017  22          ADC    MOV  %>03,A      Put 03 in register A
0030      F018  03
0031      F019  A2          CSHIGH MOVP %>01,APORT TLV1549 Chip Select goes high
0031      F01A  01
0031      F01B  04
0032      F01C  B2          DEC  A          Decrement the contents of Register A by 1
0033      F01D  E6          JNZ  CSHIGH      and jump to CSHIGH if result is not zero
0033      F01E  FA
0034      F01F  A2          MOVP %>00,APORT TLV1549 Chip Select goes low
0034      F020  00
0034      F021  04
0035      F022  A2          MOVP %>16,SCTL0 Set up Serial Control Register 0
0035      F023  16
0035      F024  15
0036      F025  A2          MOVP %>C0,SCTL1 Set up Serial Control Register 1
0036      F026  C0
0036      F027  18
0037      F028  80          LABEL1 MOVP SSTAT,A      Put contents of Serial Status Register in A
0037      F029  16
0038      F02A  26          BTJO %>2,A,LABEL2 If bit 1 of A is 1, jump to LABEL2
0038      F02B  02
0038      F02C  02
0039      F02D  E0          JMP  LABEL1      and if not, jump to LABEL1
0039      F02E  F9
0040      F02F  80          LABEL2 MOVP RXBUF,A      Put contents of RXBUF (MSByte) in A
0040      F030  19
0041      F031  D0          MOV  A,R10      Put contents of A into Register 10
0041      F032  0A
0042      F033  A2          MOVP %>16,SCTL0 Set up Serial Control Register 0
0042      F034  16
0042      F035  15

```

```

0043 F036 A2          MOV  %>C0,SCTL1  Set up Serial Control Register 1
      F037 C0
      F038 18
0044 F039 80 LABEL3  MOV  SSTAT,A    Put contents of Serial Status Register in A
      F03A 16
0045 F03B 26          BTJO %>2,A,LABEL4  If bit 1 of A is 1, jump to LABEL1
      F03C 02
      F03D 02
0046 F03E E0          JMP  LABEL3      and if not, jump to LABEL3
      F03F F9
0047 F040 80 LABEL4  MOV  RXBUF,A    Put contents of RXBUF (LSByte) in A
      F041 19
0048 F042 D0          MOV  A,R11      Put contents of A in Register 11
      F043 0B
0049 F044 D2          DEC  COUNT      (COUNT) - 1
      F045 09
0050 F046 E6          JNZ  ADC        If COUNT is not zero do another conversion
      F047 CF
0051 F048 B0          CLRC           clear carry bit
0052 F049 DD          RRC  R11      * * * * *
      F04A 0B          *
0053 F04B E7          JNC  LSBIT0    * Reformats Least Significant Byte *
      F04C 03          *
0054 F04D 74          OR   %>2,R11   * * * * *
      F04E 02
      F04F 0B
0055 F050 42 LABEL4  MOV  R11,LSBYTE Put reformatted LSByte in LSBYTE
      F051 0B
      F052 11
0056 F053 D5          CLR  R12      clear register 12
      F054 0C
0057 F055 D5          CLR  R14      and register 14
      F056 0E
0058 F057 22          MOV  %>8,A     Set contents of A to 8
      F058 08
0059 F059 42          MOV  R10,R12  Put contents of register 10 in register 12
      F05A 0A
      F05B 0C
0060 F05C B0 LABEL4  CLRC           * * * * *
0061 F05D DD          RRC  R12      *
      F05E 0C          *
0062 F05F DF          RLC  R14      * Reformats Most Significant Byte *
      F060 0E          *
0063 F061 B2          DEC  A        *
0064 F062 E6          JNZ  FORMAT   * * * * *
      F063 F8
0065 F064 42          MOV  R14,MSBYTE Put reformatted MSByte into MSBYTE
      F065 0E
      F066 10
0066 F067 0A          RETS          Return from subroutine ADC
0067 FFFE          AORG >FFFE   Configure Reset vector
0068 FFFE F006      DATA START  to point to START
0069

```

TLV1549-TO-80C51-L INTERFACE

Microcontroller Features

The 80C51-L is the 3.3-V supply version of the 80C51 family of microcontrollers. Various 3.3-V supply versions of the 80C51 architecture are available from different manufacturers. Individual data sheets should be consulted to establish at which maximum crystal frequency each specific device type can operate.

As indicated for the previously described interfaces, the most suitable method of receiving the serial output from the TLV1549 is to configure the serial port of the microcontroller to perform like an 8-bit shift register. The same is true for the 80C51-L.

Serial I/O Mode 0

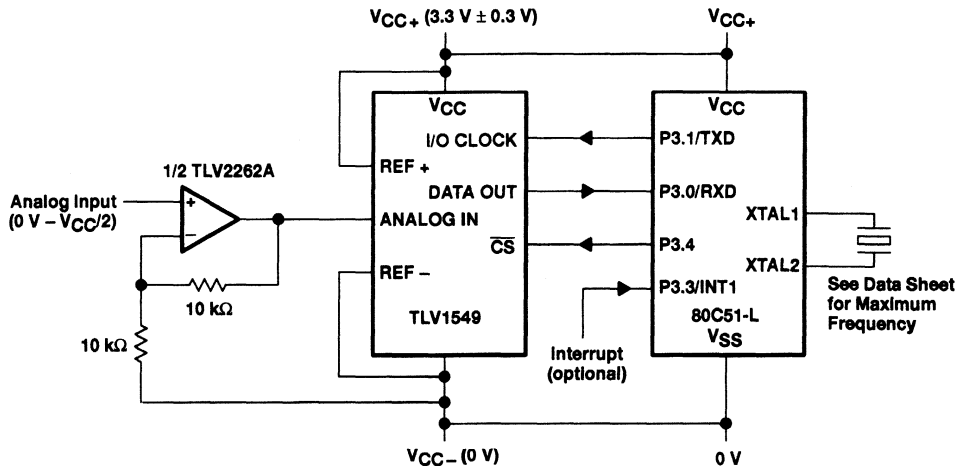
The type of serial communication to and from the 80C51-L is determined by the data inserted into the serial port control register (SCON). The contents of the most significant bits of SCON (bits 7 and 6) determine the operating mode (modes 0, 1, 2, and 3) of the serial port.

Mode 0 is the shift register mode and is programmed by placing a 0 in each of bits 7 and 6 of the SCON. Bit 4 (REN) of the SCON is the receive enable bit. This bit is set to 1, while bit 1 (RI) of the SCON is 0, to receive serial data. In this configuration, data is received at bit 0 of port 3 (P3.0). The synchronizing signal for clocking in this data is output at TXD, which is bit 1 of port 3 (P3.1).

When configured for mode 0, eight bits are received with no trailing stop bit for each enabling of serial reception. The data is received with the least significant bit expected first, the reverse of the order in which the TLV1549 serial data arrives. Reformatting of the received data is therefore necessary.

Interface Circuit

Figure 5 shows the interconnections necessary to implement the interface of the TLV1549 to the 80C51-L microcontroller. \overline{CS} of the TLV1549 is driven by bit 4 of port 3 (P3.4) of the 80C51-L.



NOTE: I/O clock frequency = microcontroller clock frequency/12

Figure 5. TLV1549 10-Bit Serial Out ADC-to-80C51-L Microcontroller Interface

Software Listing

Similar to the previously described program listings, the following listing contains the subroutine ADC that reads into the 80C51-L ten bits of serial data resulting from a single conversion of the TLV1549. The number of consecutive conversions performed for each jump to subroutine ADC is equal to the number placed in COUNT. The result of each conversion is overwritten by that of the next conversion in the sequence.

Program Listing for the TLV1549-to-80C51-L Interface

```

LOC   OBJ   LINE  SOURCE
1     ; * * * * *
2     ; *
3     ; *           TLV1549 - 80C51-L Interface Program
4     ; *
5     ; *   This program contains a subroutine ADC which reads
6     ; *   in the serial data from the TLV1549 10-bit ADC
7     ; *   and places the most significant byte in address 20H
8     ; *   and least significant byte in address 21H
9     ; *
10    ; * * * * *
11
12    0020  MSBYTE  EQU 20H      ; * * * * *
13    0021  LSBYTE  EQU 21H      ; *   Name data destinations
14    REG    COUNT  EQU R3      ; *   and COUNT register
15
16    0022                ORG 22H      ; Set start address
17    0022  7B02  START:  MOV COUNT, #02H ; Set COUNT=2 (Do 2 conversions)
18    0024  020029 JMP ADC      ; Jump to subroutine ADC
19    0027  80F9  JMP START  ; Repeat above again
20    0029  D2B4  ADC:    SETB P3.4    ; * * * * *
21    002B  7410  MOV A, #10H      ; * Set Port3 (bit 4) high
22    002D  14    DELAY:  DEC A        ; * (Sets CS of TLV1549 high)
23    002E  70FD  JNZ DELAY  ; * * * * *
24    0030  C2B4  CLR P3.4
25    0032  759810 MOV SCON, #10H
26    0035  3098FD LABEL1: JNB SCON.0, LABEL1 ; Read in
27    0038  C298  CLR SCON.0      ; most significant
28    003A  A899  MOV R0, SBUF      ; byte, place in R0
29    003C  3098FD LABEL2: JNB SCON.0, LABEL2 ; Read in
30    003F  C29C  CLR SCON.4      ; least significant
31    0041  C298  CLR SCON.0      ; byte,
32    0043  A999  MOV R1, SBUF      ; place in R1
33    0045  1B    DEC COUNT      ; COUNT-1
34    0046  EB    MOV A, COUNT
35    0047  70E0  JNZ ADC        ;
36
37    0049  7C08  MOV R4, #08H      ; If COUNT not = 0,
38    004B  AA00  MOV R2, 00H      ; do another conversion
39    004D  C3    LOOP:   CLR C        ; Put 08H in R4
40    004E  E8    MOV A, R0      ; * * * * *
41    004F  13    RRC A        ; *
42    0050  F8    MOV R0, A      ; *           Reformats MSByte
43    0051  EA    MOV A, R2      ; *
44    0052  33    RLC A        ; *
45    0053  FA    MOV R2, A      ; *
46    0054  1C    DEC R4        ; *
47    0055  EC    MOV A, R4      ; *
48    0056  70F5  JNZ LOOP      ; * * * * *
49    0058  EA    MOV A, R2      ;
50    0059  F520  MOV 20H, A      ;
51    005B  E9    MOV A, R1      ; * * * * *
52    005C  13    RRC A        ; *
53    005D  F521  MOV 21H, A      ; *           Reformats LSByte
54    005F  9209  MOV 21H.1, C    ; *
55    0061  C20F  CLR 21H.7      ; * * * * *
56    0063  22    RET          ; Return from subroutine
57    END

```

ANALOG CONSIDERATIONS

Analog Reference for the TLV1549

The REF+ terminal of the TLV1549 can be directly connected to the V_{CC} rail of the device. This produces accurate results for analog input signals right up to the supply rail. However, if the operational amplifier driving the input is supplied from the same single supply as the ADC, the output of the operational amplifier could possibly be nonlinear up to the rail voltage. If this is a concern, a lower reference voltage as shown in Figure 6 can be applied to REF+ providing more headroom for the amplifier.

The output of the TL2262A 3-V single-supply operational amplifier can swing to within 10 mV of its positive supply rail. This effectively loses only two least significant bits (LSBs) off the top of the digital output range of the TLV1549 when both the amplifier and ADC are powered from the same 3-V supply. The circuit shown in Figure 6 provides a 2.5-V reference to the converter, which restores those bits to the digital output of the TLV1549 while the maximum analog input swing is reduced to 2.5 V.

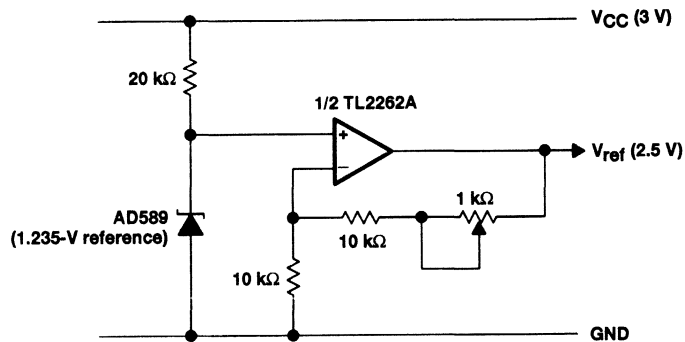


Figure 6. User Adjustable 2.5-V Reference Circuit

PCB Layout

As with all precision analog components, care should be taken in laying out the printed-circuit board (PCB) on which the TLV1549 and chosen microcontroller are placed. The interaction between digital and analog signal paths should be minimized by keeping them as far apart as is physically possible within the constraints of the dimensions of the PCB.

Grounding and Decoupling

Each supply terminal to both the TLV1549 and the microcontroller should be decoupled by a ceramic capacitor of approximately 100 nF in value, situated close to the terminal of the device. Digital and analog ground return paths should be kept separate to prevent any digitally generated currents from corrupting the analog signal.

APPENDIX A

References

MC68HC705C8 Technical Data Manual (1990)
M68HC05 Applications Guide
TLV1549 Data Sheet
TMS7000 Family Data Manual (1991)
Embedded Microcontrollers and Processors Vol. 1

Motorola
Motorola
Texas Instruments Incorporated
Texas Instruments Incorporated
Intel Corporation

TLC2932

Phase-Locked-Loop Building Block With Analog Voltage-Controlled Oscillator and Phase Frequency Detector



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1 INTRODUCTION

The TLC2932IPW integrated circuit (IC) contains a voltage-controlled oscillator (VCO) and a phase frequency detector (PFD) for use in phase-locked-loop (PLL) circuit blocks. A standalone PLL circuit can be designed with the addition of an external frequency divider and a loop filter.

Because the on-chip analog VCO has a wide usable lock frequency range and can cover a wide range of frequencies (11 MHz–50 MHz) previously unavailable, many new applications are now possible. A stable clock output can be achieved with only one external resistor required for the oscillator. The on-chip PFD uses a widely accepted edge-triggered charge pump circuit. The TLC2932IPW is designed for use as clock frequency generator blocks in digital signal processor (DSP) applications involving video where many video signal frequency bands are possible. Refer to the TLC2932 data sheet (SLAS097) for other features.

For the proper usage of the TLC2932IPW, basic concepts relating to conventional PLL blocks and examples based on experimental results are described in this application report. In the design of a high performance PLL circuit, the parameters of the peripheral circuits such as the counter frequency division setting and the loop filter parameters are determined by the application. The fundamentals needed to produce a high performance PLL are discussed, and the VCO, PFD, frequency divider, and loop filter are examined individually and then as a group.

2 THEORY OF AN ANALOG PHASE-LOCKED LOOP (PLL)

2.1 Overview

A phase-locked loop is a feedback controlled circuit that maintains a constant phase difference between a reference signal and an oscillator output signal.

2.2 General Operation of a PLL

Figure 2–1 shows a basic block diagram of a PLL. A phase frequency detector compares the phase of the VCO output frequency, f_{osc} , with the phase of a reference signal frequency, f_{ref} . A phase detector output pulse is generated in proportion to that phase difference. This pulse is smoothed by passing it through a loop filter. The resulting dc component is used as the input voltage for controlling the VCO. The output of the VCO, f_{osc} , is fed back to the phase frequency detector input for comparison which in turn controls the VCO oscillating frequency to minimize the phase difference. Therefore, both frequency and phase are made the same, i.e., $f_{osc} = f_{ref}$ and $\theta_{osc} = \theta_{ref}$, such that the phase and frequency of the VCO and the reference signal source are in a locked state.

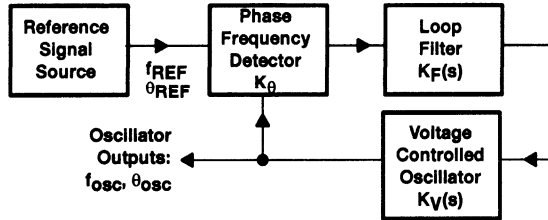


Figure 2–1. Basic PLL Block Diagram

Therefore, the PLL is a negative feedback circuit which compares the current value to a reference value to make the difference as close to zero as possible.

2.2.1 Analysis of a PLL as a Feedback Control System

An analysis can be performed using the linearized block diagram in Figure 2–2.

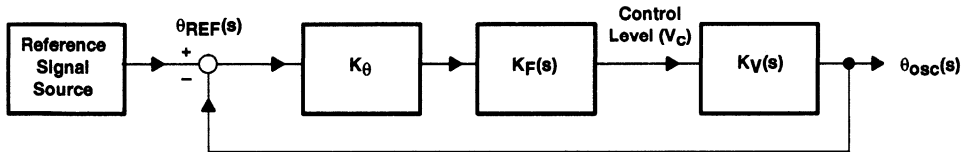


Figure 2–2. Linearized PLL Block Diagram

The parameters in Figure 2–2 are defined as follows:

- K_θ = gain of the phase frequency detector (V/rad)
- K_F = transfer function of the loop filter (V/V)
- V_c = VCO control level
- V_c = VCO control level
- s = Laplace variable

Using a Laplace transform, the closed-loop transfer function can be expressed as:

$$\frac{\theta_{osc}(s)}{\theta_{REF}(s)} = \frac{K_\theta \times K_F(s) \times K_V(s)}{1 + K_\theta \times K_F(s) \times K_V(s)} = W(s) \quad (2.1)$$

The VCO transform gain, K_V , is a function of time. Since phase is the time integral of frequency, the gain can be expressed as follows:

$$K_V(s) = \frac{K_V}{s} \quad (2.2)$$

The phase frequency detector gain is assumed to not be a function of frequency.

From equation 2.1 and equation 2.2

$$W(s) = \frac{K_{\theta} \times K_F(s) \times K_V}{s + K_{\theta} \times K_F(s) \times K_V} \quad (2.3)$$

This equation is the general linear transfer function for a PLL.

The PLL has become widely used as a frequency synthesizer by generating frequencies from a single reference signal source such as a crystal oscillator.

Consider the operation of the PLL frequency synthesizer in Figure 2–3.

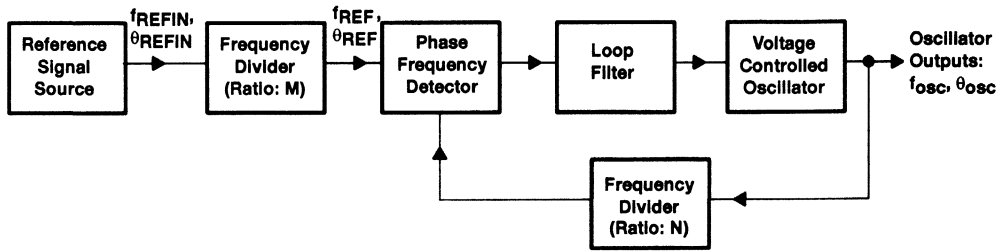


Figure 2–3. PLL Frequency Synthesizer Block Diagram

Since the signal from the reference signal source is used to generate the desired frequency in a frequency synthesizer, only frequencies at multiples of the reference frequency can be obtained.

The phase frequency detector compares the signal from the 1/N frequency divider which divides the output signal of the VCO, and the signal from the 1/M frequency divider which divides the output signal of the reference signal source, and controls the VCO frequency in such a way so that both frequency and phase are the same.

Therefore $\frac{f_{\text{refin}}}{M} = \frac{f_{\text{osc}}}{N}$ (2.4)

and the oscillating frequency, $f_{\text{osc}} = f_{\text{refin}} \times \frac{N}{M}$ (2.5)

The closed-loop transfer function of the PLL in equation 2.1 can now be considered. If 1/M and 1/N frequency dividers are inserted into the block diagram of Figure 2–3, then Figure 2–2 becomes Figure 2–4.

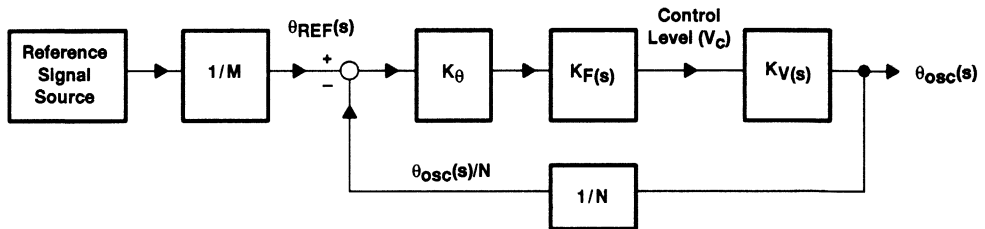


Figure 2–4. Linearized PLL Frequency Synthesizer Block Diagram

Thus, the closed-loop transfer function can be expressed by the following equation:

$$W(s) = \frac{K_{\theta} \times K_F(s) \times K_V}{s + \frac{K_{\theta} \times K_F(s) \times K_V}{N}} \quad (2.6)$$

If the multiplication parameter N is set to 1 in equation 2.6, it becomes equation 2.3.

In this application report, equation 2.6 is used as the closed-loop transfer function for the PLL.

From equations 2.3 and 2.6, the closed-loop transfer function of the PLL is heavily dependent on the characteristics of the loop filter which is discussed later in this application report.

2.2.2 Definitions

2.2.2.1 Free Running Frequency

The free oscillating frequency of the VCO when it is in an unlocked state is called the free running frequency.

2.2.2.2 Hold-In Range (Lock Range) and Lock-In Range (Capture Range)

When the PLL is in the phase-locked state, the frequency range in which the frequency of the input reference signal, f_{REF} can slowly be pulled away from the free running frequency of the VCO but still maintain the phase-locked condition is called the hold-in range or lock range. When the PLL is not in the phase-locked state, if the frequency of the input signal, f_{REF} slowly approaches the free running frequency of the VCO, the frequency range in which the input signal becomes phase-locked is called the lock-in range or capture range.

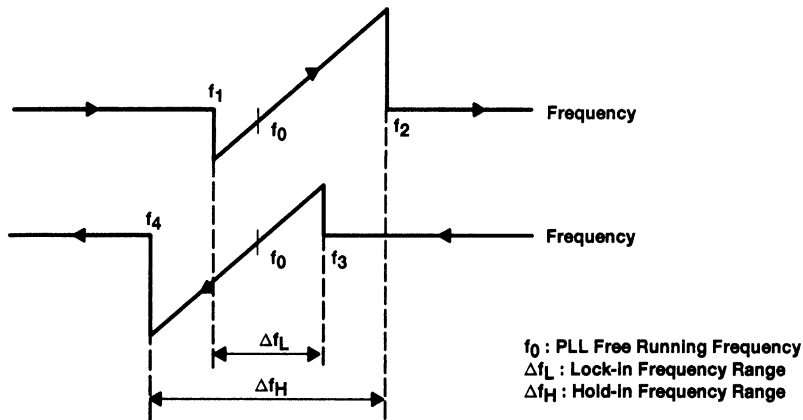


Figure 2-5. Concept Behind Hold-In Range and Lock-In Range

Referring to the conceptual diagram in Figure 2-5, if the input signal frequency is increased slowly from a very low frequency not phase-locked to the VCO free running frequency, phase-lock occurs at frequency f_1 . If the input signal frequency continually increases, it will pass through the free running frequency and then become unlocked at frequency f_2 . Conversely, if the input signal frequency is decreased slowly from a very high frequency not phase-locked to the VCO free running frequency, phase lock occurs at frequency f_3 . If the input signal frequency continually increases, it will pass through the free running frequency and the PLL becomes unlocked at frequency f_4 . The hold-in range, Δf_H , and lock-in range, Δf_L , can be expressed as the following equations:

$$\Delta f_H = (f_2 - f_4) \quad (2.7)$$

$$\Delta f_L = (f_3 - f_1) \quad (2.8)$$

Normally, the relationship of $\Delta f_H > \Delta f_L$ exists.

2.2.2.3 Lock-Up Time (Acquisition Time)

The amount of time required for the loop to phase lock is called lock-up time or acquisition time.

2.3 PLL Functional Blocks

2.3.1 Voltage-Controlled Oscillator (VCO)

The VCO is an oscillator circuit with the following characteristics whose output frequency is controlled by a voltage.

- K_V = VCO gain (rad/V/sec) from Section 2.2.1
- Stable with respect to external disturbances (change in voltage, temperature, etc.)
- Control voltage versus oscillating frequency should ideally be linear
- Frequency adjustment should be simple

Because it is extremely difficult to satisfy all these conditions at the same time, a suitable oscillator should be chosen based on the application.

Oscillators that are typically used include the following:

- Crystal oscillator
- LC oscillator
- CR oscillator

For a VCO utilizing any of the above oscillation techniques, many excellent technical books and articles on VCO circuit design should be used.

2.3.2 Phase Detector Operation and Types

A phase detector detects phase differences between two input signals and produces a voltage based on this phase difference.

Phase detectors can be either analog or digital. For analog, representative devices are ring modulators and multipliers which are also called double balanced mixers. For digital, representative devices are OR-gates, ExOR-gates, RS flip-flops, 3-state buffers, and phase frequency detectors.

Only the digital phase detectors are discussed in this application report.

2.3.2.1 OR-Gate Type Phase Detector

The simplest form of digital type phase detectors is the OR-gate type shown in Figure 2-6(a).

For an OR-gate type phase detector, the output signal duty cycle varies depending on the phase difference, as shown in Figure 2-6(b). Then this output signal is smoothed by an integrator. The resulting output voltage in relation to the phase difference is shown in Figure 2-6(c).

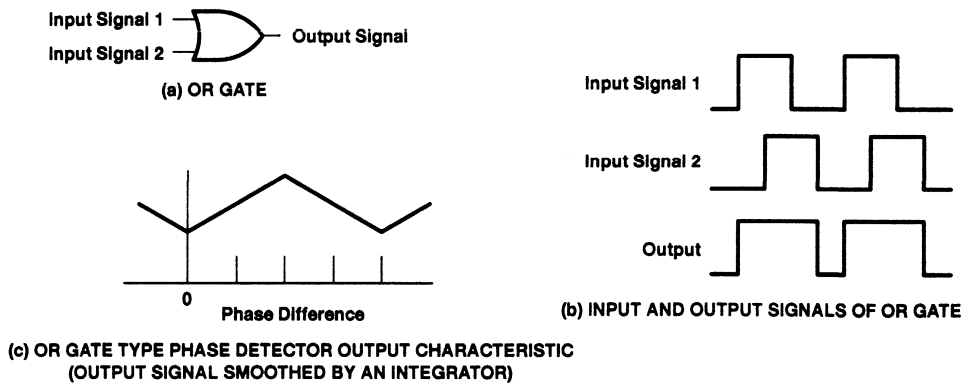
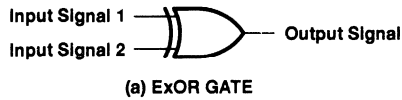


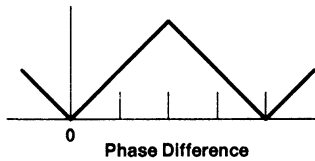
Figure 2-6. OR Gate Type Phase Detector

2.3.2.2 ExOR-Gate Type Phase Detector

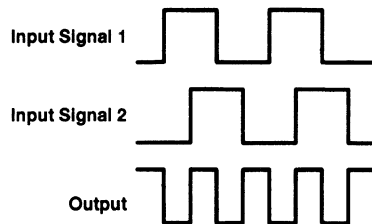
An ExOR gate phase detector is shown in Figure 2-7(a).



(a) ExOR GATE



(c) ExOR GATE TYPE PHASE DETECTOR OUTPUT CHARACTERISTIC (OUTPUT SIGNAL SMOOTHED BY AN INTEGRATOR)



(b) ExOR GATE INPUT AND OUTPUT SIGNALS

Figure 2-7. ExOR Gate Type Phase Detector

For this type of phase detector, the duty cycle of the output signal varies depending on the phase difference, as shown in Figure 2-7(b). This output signal is also smoothed by an integrator. The resulting output voltage in relation to the phase difference is shown in Figure 2-7(c).

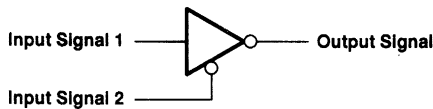
For this ExOR-gate type of phase detector, as compared to an OR-gate type of phase detector, the integrator output signal swings from 0 V to the supply voltage, V_{DD} . Moreover, because the ExOR-gate output frequency is twice that of the OR-gate, the high frequency components are more easily filtered out by the integrator.

However, when using an ExOR-gate as a phase detector, if each input signal duty cycle is not 50%, the output voltage generated from the phase difference does not have acceptable linear characteristics. Therefore, care must be exercised when using this type of phase detector.

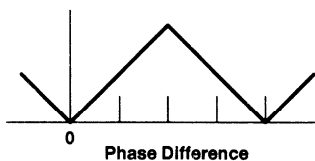
2.3.2.3 3-State Buffer Type Phase Detector

A 3-state buffer phase detector is shown in Figure 2-8(a).

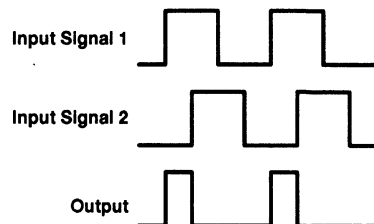
The 3-state buffer phase detector output characteristic, as shown in Figure 2-8(c), is basically the same as ExOR gate phase detector. However, when input signal 2 is high, the output is in a high impedance state as shown in Figure 2-8(b).



(a) 3-STATE BUFFER



(c) 3-STATE BUFFER TYPE PHASE DETECTOR OUTPUT CHARACTERISTIC (OUTPUT SIGNAL SMOOTHED BY AN INTEGRATOR)



(b) 3-STATE BUFFER INPUT AND OUTPUT SIGNALS (OUTPUT HIGH IMPEDANCE WHEN INPUT SIGNAL 2 IS HIGH)

Figure 2-8. 3-State Buffer Type Phase Detector

2.3.2.4 R-S Flip-Flop Type Phase Detector

A R-S flip-flop phase detector is shown in Figure 2-9, and the input and output signals are shown in Figure 2-9(b).

As shown in Figure 2-9(c), a RS flip-flop type phase detector has twice the comparison range of an ExOR gate type phase detector.

The R-S flip-flop type phase detector can be constructed using only an R-S flip flop. The pulse width of the input signal pulses is small, so a SET-RESET error difference do not cause a significant error. This condition can be solved by inserting AND-gates as shown in Figure 2-9(a).

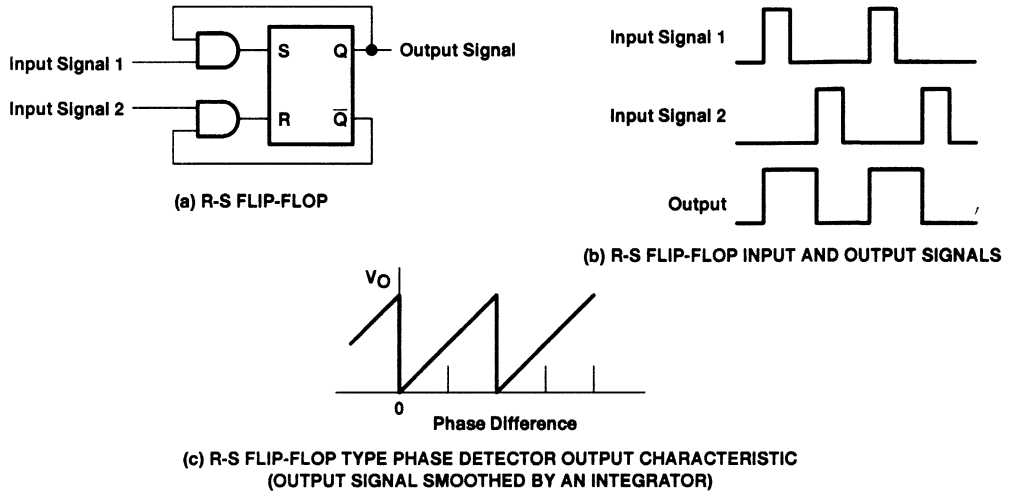


Figure 2-9. RS Flip-Flop Type Phase Detector

2.3.2.5 Phase Frequency Detector (PFD)

Of the phase detectors currently available, the most commonly used in a PLL is a circuit called a phase frequency detector. Figure 2-10(a) shows an example of a phase frequency detector.

In Figure 2-10(b), when the input signal 2 phase lags that of input signal 1, phase detector output D goes high starting from the rising edge of input signal 1 to the rising edge of input signal 2, that is, during the period of time corresponding to a phase difference between inputs 1 and 2, output D goes high. During this same period, output U stays low. When the phase of input 2 leads that of input 1, output D stays low from the rising edge of input 2 to the rising edge of input 1. During that time, U goes high.

When both inputs 1 and 2 have the same phase, both outputs D and U stay low. Depending on the phase detector outputs D and U, the charge pump MOS transistors are turned on and off resulting in output levels of V_{OH} , V_{OL} , or high impedance. So when D is high and U is low, the MOS transistor Q_1 is on and Q_2 is off, therefore, the output level is V_{OH} . When U is high and D is low, Q_2 is on and Q_1 is off, resulting in the output level of V_{OL} . When both D and U are low, Q_1 and Q_2 are both off and the output becomes high impedance.

In this way, the output level is proportional to the phase difference. The output signal characteristic is shown in Figure 2-10(c).

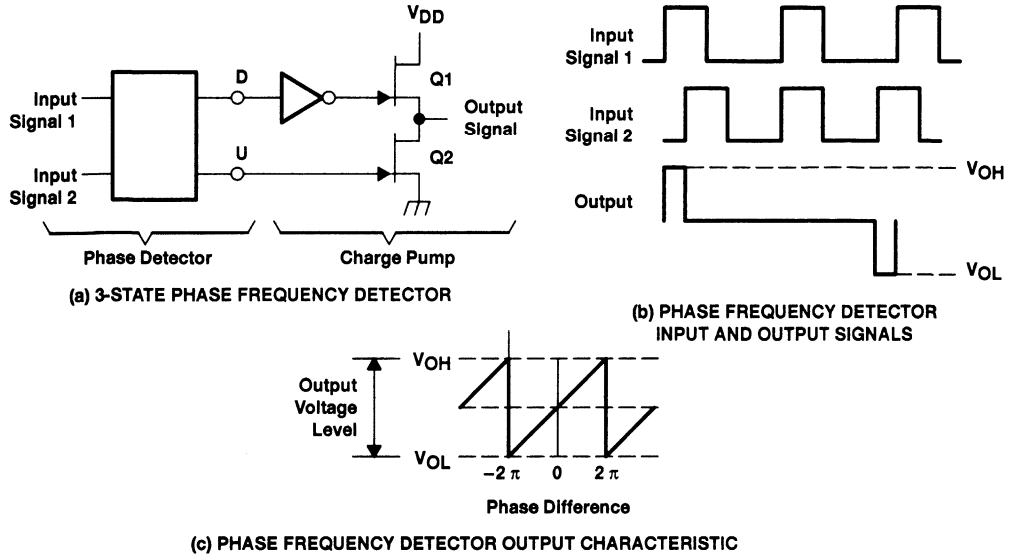


Figure 2-10. 3-State Phase Frequency Detector

2.4 Loop Filter

The loop filter smooths the output pulses of the phase detector and the resulting dc component is the VCO input. From the closed-loop transfer function (equation 2.6) obviously the loop filter is very important in determining the characteristics of the PLL response.

Some examples of a loop filter are a lag filter, a lag-lead filter, and an active filter. Among these, the most commonly used are the lag-lead filter and the active filter. For these two filters, the PLL closed loop transfer functions are derived, and design examples for the filter parameters are shown.

2.5 Transfer Function Using a Lag-Lead Filter

First, the lag-lead filter transfer function is derived from Figure 2-11. If a Laplace transform is taken, then

$$\frac{V_o}{V_D} = K_F(s) = \frac{1 + sC1 \times R2}{1 + sC1(R1 + R2)} = \frac{1 + \tau_2}{1 + s(\tau_1 + \tau_T)} \quad (2.9)$$

Where

$$\tau_1 = C1 \times R1, \tau_2 = C1 \times R2 \quad (2.10)$$

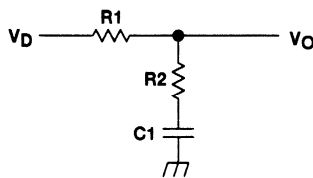


Figure 2-11. Lag-Lead Filter

By substituting equation 2.9 into equation 2.6 and rearranging the terms, the PLL closed-loop transfer function is

$$W(s) = \frac{1 + s\tau_2}{\left\{(\tau_1 + \tau_2)/K\right\} \times s^2 + \left\{(N + K \times \tau_2)/(N \times K)\right\} \times s + 1/N} \quad (2.11)$$

Where

$$K_\theta \times K_V = K \quad (2.12)$$

If this equation is further expanded, it becomes

$$W(s) = W_1(s) + W_2(s) = \frac{1}{\left\{(\tau_1 + \tau_2)/K\right\} \times s^2 + \left\{(N + K \times \tau_2)/(N \times K)\right\} \times s + 1/N} + \frac{s\tau_2}{\left\{(\tau_1 + \tau_2)/K\right\} \times s^2 + \left\{(N + K \times \tau_2)/(N \times K)\right\} \times s + 1/N} \quad (2.13)$$

The general transfer function for a second order system is shown below

$$G(s) = \frac{1}{(1/\omega_n^2) \times s^2 + (2\zeta/\omega_n) \times s + 1} \quad (2.14)$$

Where ω_n is the natural angular frequency and ζ is the damping factor.

If, in equation 2.15 the right hand side first term is designated as $W_1(s)$ and the second term as $W_2(s)$, then $W_1(s)$ is a second order system as in equation 2.14 and $W_2(s)$ is a second order lag with gain of τ_2 multiplied by s .

If $W_1(s)$ is equated to equation 2.14 and the coefficients compared

$$W_1(s) = \frac{1 + s\tau_2}{\left\{(\tau_1 + \tau_2)/K\right\} \times s^2 + \left\{(N + K \times \tau_2)/(N \times K)\right\} \times s + 1/N} = \frac{1}{(1/\omega_n^2) \times s^2 + (2\zeta/\omega_n) \times s + 1} \quad (2.15)$$

the following are derived

$$\omega_n = \sqrt{\frac{K}{N(\tau_1 + \tau_2)}} \quad (2.16)$$

$$\zeta = \frac{1 + K\tau_2}{2\sqrt{N(\tau_1 + \tau_2)} \times K} = \frac{\omega_n}{2} \left(\tau_2 + \frac{N}{K} \right) \quad (2.17)$$

Similarly for $W_2(s)$

$$W_2(s) = \frac{s\tau_2}{\left\{(\tau_1 + \tau_2)/K\right\} \times s^2 + \left\{(N + K \times \tau_2)/(N \times K)\right\} \times s + 1/N} = \frac{(2\zeta/\omega_n - N/K) \times s}{(1/\omega_n^2) \times s^2 + (2\zeta/\omega_n) \times s + 1} \quad (2.18)$$

Thus, using a lag-lead filter, the PLL closed-loop transfer function becomes

$$W(s) = W_1(s) + W_2(s) = \frac{1 + (2\zeta/\omega_n - N/K) \times s}{(1/\omega_n^2) \times s^2 + (2\zeta/\omega_n) \times s + 1} \quad (2.19)$$

From the above result, design equations for lag-lead filter parameters are derived.

If $\tau_1 = C1 \times R1$ and $\tau_2 = C2 \times R2$ are substituted into equations 2.16 and 2.17 respectively and solved for R1 and R2, the following equations are derived:

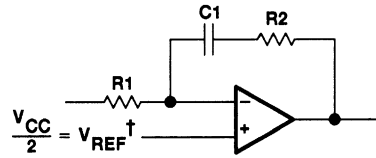
$$R1 = \left(\frac{K}{\omega_n^2} \times \frac{1}{N} - \frac{2\zeta}{\omega_n} + \frac{N}{K} \right) \times \frac{1}{C1} \quad (2.20)$$

$$R2 = \left(\frac{2\zeta}{\omega_n} - \frac{N}{K} \right) \times \frac{1}{C1} \quad (2.21)$$

2.6 Transfer Function Using an Active Filter

When using an active filter, the PLL closed-loop transfer function and design equation for filter parameters are derived in the same fashion as in Section 2.5.

First, the Laplace transform is taken and the transfer function of an active filter is derived. Figure 2–12 shows an example of an active filter.



† Voltage used for single ended power supply systems.

Figure 2–12. Active Filter

The transfer function for the active filter is

$$K_F(s) = \frac{1 + sC1 \times R2}{sC1(R1 + R2)} = \frac{1 + s\tau_2}{s\tau_1} \quad (2.22)$$

Where

$$\tau_1 = C1 \times R1 \text{ and } \tau_2 = C1 \times R2 \quad (2.23)$$

From the PLL closed-loop transfer function, if $K_F(s)$ is substituted into equation 2.6 and equation 2.6 is simplified, it becomes

$$W(s) = \frac{1 + s\tau_2}{\left(\tau_1/K\right) \times s^2 + \left(\tau_2/N\right) \times s + 1/N} \quad (2.24)$$

Where

$$K_\theta \times K_V = K \text{ as before.} \quad (2.25)$$

If this equation is expanded further, it becomes

$$W(s) = W_1(s) + W_2(s) = \frac{1}{\left(\tau_1/K\right) \times s^2 + \left(\tau_2/N\right) \times s + 1/N} + \frac{s\tau_2}{\left(\tau_1/K\right) \times s^2 + \left(\tau_2/N\right) \times s + 1/N} \quad (2.26)$$

As shown before, second order lag resonators can be expressed as equation 2.14.

Following the procedure in Section 2.5.

If $W_1(s)$ is equated to equation 2.14

$$W_1(s) = \frac{1}{\left(\tau_1/K\right) \times s^2 + \left(\tau_2/N\right) \times s + 1/N} = \frac{1}{\left(1/\omega_n^2\right) \times s^2 + \left(2\zeta/\omega_n\right) \times s + 1} \quad (2.27)$$

the following are derived

$$\omega_n = \sqrt{\frac{K}{N \tau_1}} \quad (2.28)$$

$$\zeta = \frac{\tau_2}{2N} = \sqrt{\tau_1/(N/K)} = \frac{\omega_n}{2} \tau_2 \quad (2.29)$$

Similarly for $W_2(s)$

$$W_2(s) = \frac{s\tau_2}{\left(\tau_1/K\right) \times s^2 + \left(\tau_2/N\right) \times s + 1/N} = \frac{\left(2\zeta/\omega_n\right) \times s}{\left(1/\omega_n^2\right) \times s^2 + \left(2\zeta/\omega_n\right) \times s + 1} \quad (2.30)$$

Thus for the active filter, the PLL closed-loop transfer function becomes

$$W(s) = W_1(s) + W_2(s) = \frac{1 + \left(2\zeta/\omega_n\right) \times s}{\left(1/\omega_n^2\right) \times s^2 + \left(2\zeta/\omega_n\right) \times s + 1} \quad (2.31)$$

From the above result, the design equation for active filter parameters can be derived.

If $\tau_1 = C1 \times R1$ and $\tau_2 = C1 \times R2$ are substituted into equations 2.28 and 2.29 respectively, and solved for R1 and R2, the following two equations are derived:

$$R1 = \frac{K}{\omega_n^2} \times \frac{1}{N} \times \frac{1}{C1} \quad (2.32)$$

$$R2 = \frac{2\zeta}{\omega_n} \times \frac{1}{C1} \quad (2.33)$$

2.7 General Design Procedures

Based on a PLL step response, the damping factor can be chosen, the natural angular frequency can be evaluated, and the characteristics of response time and relative stability can be examined. For the PLL transfer function in equation 2.31, the step responses of several cases are shown in Figure 2-13. As shown, the smaller the ζ value the larger the ringing, and a large ζ value results in little or no ringing. Also, a larger ω_n results in a faster response time.

The step response for a PLL using an active filter as a loop filter is shown in Figure 2-13. When a passive lag-lead filter is used, if the condition $\omega_n \ll K/N$ is met for equation 2.19, the step response is similar to the step response shown.

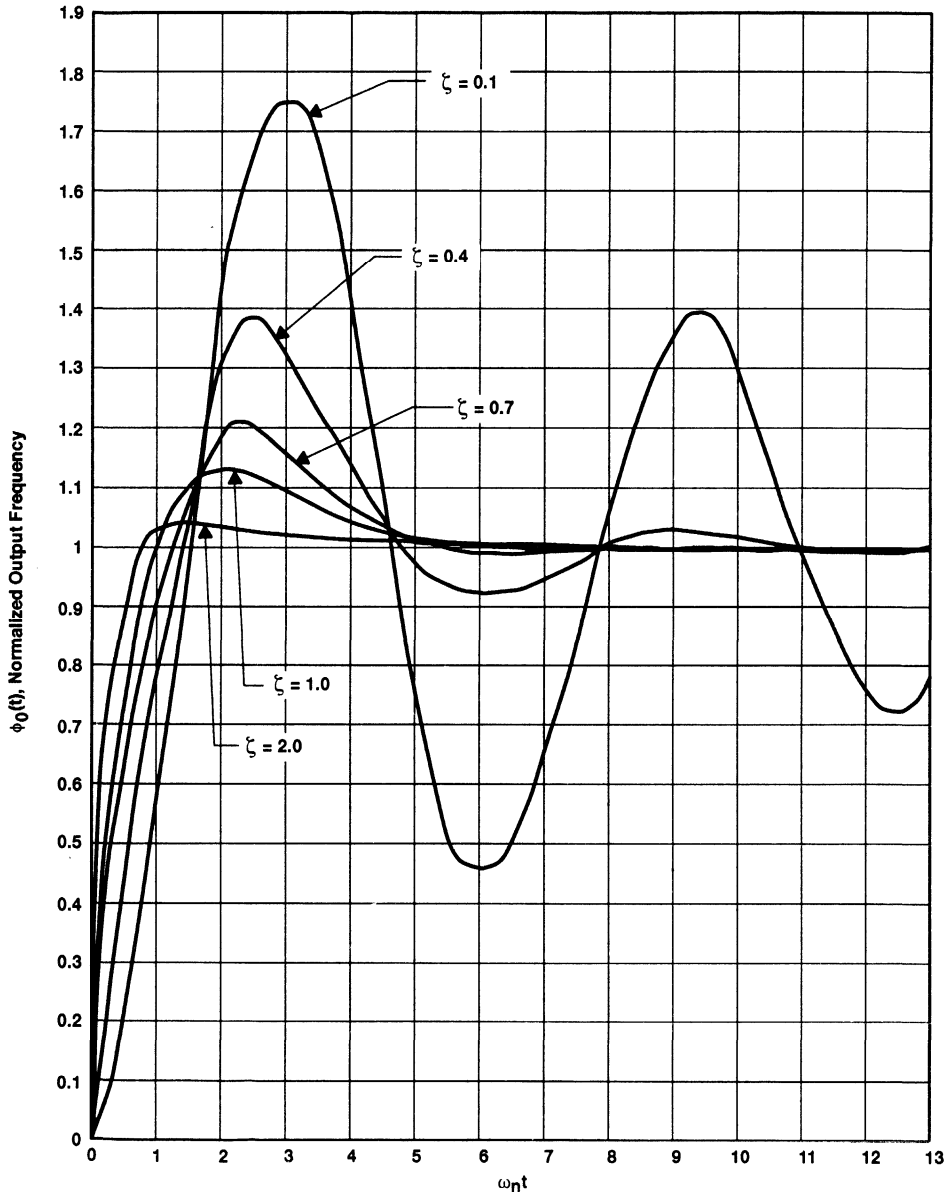


Figure 2-13. PLL Step Response Using the Active Filter in Figure 2-17

To design a PLL system, ζ is selected first. Then from the step response characteristic, the value of $\omega_n t$, at which the response is decayed to within 5% of the final value, is found. Then $\omega_n t$ is divided by the desired lock-up time, t_s , to determine ω_n . The following steps should be followed.

1. ζ is a measure of stability. and usually ζ is selected to be between 0.6 to 0.8.
2. Assume ζ is selected to be 0.7.
3. The value of $\omega_n t$ from the step response characteristic is determined to be 4.5 for response settling within 5%.
4. Lock-up time, t_s , is determined by system requirements.
5. The PLL natural angular frequency, ω_n , is

$$\omega_n = \frac{\omega_n \tau}{t_s} = \frac{4.5}{t_s} \text{ (rad/sec)} \quad (2.34)$$

This criterion varies depending on the system application. It is appropriate to pick the natural frequency ($f_n = \omega_n/2\pi$) to be one tenth to one hundredth of the reference frequency of the phase frequency detector.

6. The frequency division ratio is determined from the reference frequency and the desired frequency according to equation 2.5.
7. Determine the VCO gain parameter, K_V . An example of a VCO oscillating frequency characteristic is shown in Figure 2-14.

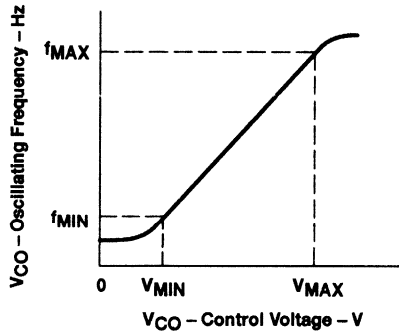


Figure 2-14. VCO Oscillating Frequency Characteristic

From the oscillating frequency characteristic of Figure 2-14, the VCO gain can be determined using the following equation:

$$K_V = \frac{f_{MAX} - f_{MIN}}{V_{MAX} - V_{MIN}} \times 2\pi \text{ [rad/sec/V]} \quad (2.35)$$

Where

f_{MAX} = maximum frequency at which the linearity of the oscillating frequency versus the VCO control voltage can be maintained.

f_{MIN} = minimum frequency at which the linearity of the oscillating frequency versus the VCO control voltage can be maintained.

V_{MAX} = control voltage at which the VCO oscillating frequency is f_{MAX}

V_{MIN} = control voltage at which the VCO oscillating frequency is f_{MIN}

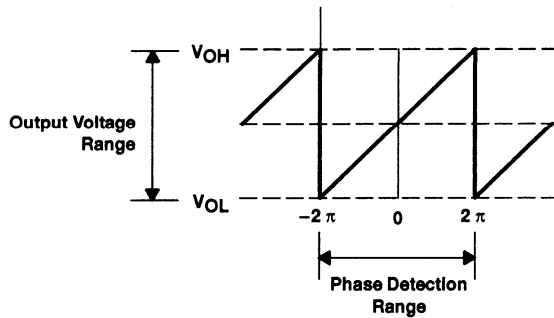


Figure 2-15. Phase Frequency Detector Output Characteristic

8. Determine the phase detector gain parameter, K_{θ}

Based on the phase frequency detector output characteristic in Figure 2-15, the phase detector gain can be determined from equation 2.36.

$$K_{\theta} = \frac{V_{OH} - V_{OL}}{4\pi} \quad [V/\text{rad}] \quad (2.36)$$

Where

V_{OH} = maximum output voltage

V_{OL} = minimum output voltage

For other types of phase detectors, the phase detector gain can be determined in the same fashion.

9. Filter parameters can be determined by substituting each of the values determined in steps 1 through 8 into the corresponding equations.

For the lag-lead filter, substituting the desired values of ω_n , ζ , N , and K into equations 2.20 and 2.21, the filter parameters can be determined by choosing an appropriate value for C_1 .

For a practical loop filter, a second order lag-lead filter with an additional capacitor C_2 , as shown in Figure 2-16, to minimize spurious noise at the VCO input should be used.

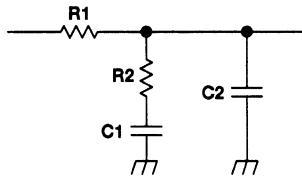


Figure 2-16. Lag-Lead Filter (With Additional Capacitor)

The value of C_2 should be less than or equal to $C_1/10$ to keep C_2 from affecting the low-pass filter response while providing adequate noise filtering.

Similarly for the case of an active filter, substituting the desired values of ω_n , ζ , N , and K into equations 2.32 and 2.33, the filter parameters can be determined by choosing an appropriate value for C_1 .

Also when using an active filter as the loop filter, as shown in Figure 2-17, a second order active filter with one additional capacitor should be used.

The additional capacitor C_2 is used for compensating the R_2 high frequency response. The cutoff frequency, ω_c , of C_2 and R_2 should be chosen to be 10 times that of the natural frequency, ω_n , of the PLL.

$$\omega_c = \frac{1}{(C_2 \times R_2)} \cong 10\omega_n \quad (2.37)$$

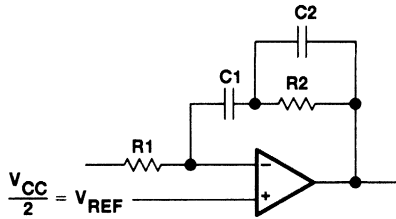


Figure 2–17. Active Filter (With Additional Capacitor)

2.8 Frequency Division

When given an input signal with frequency f , a circuit that generates a f/N (N an integer) signal synchronized to the input signal is called a frequency divider. Usually frequency dividers use programmable counters like the one shown in Figure 2–18 (programmable meaning that the frequency divide ratio N can be changed and controlled externally).

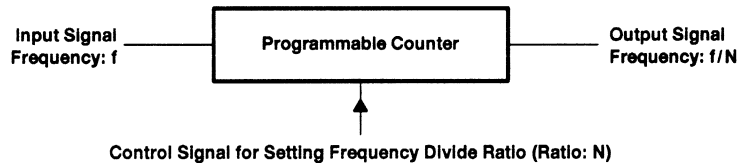


Figure 2–18. Programmable Counter

The construction of a PLL frequency divider using a programmable counter, and the prescaler and pulse swallow methods (2s modulus prescaler method) are discussed in the following sections.

2.8.1 Prescaler Method

If the frequency, f , of an input signal is too high, a divide can be added using an additional programmable counter in the feedback path. As shown in Figure 2–19, the frequency can be divided before the programmable counter using a fixed frequency divider (prescaler) operating at high speed, this lowers the input frequency to the programmable counter. This method is called the prescaler method.

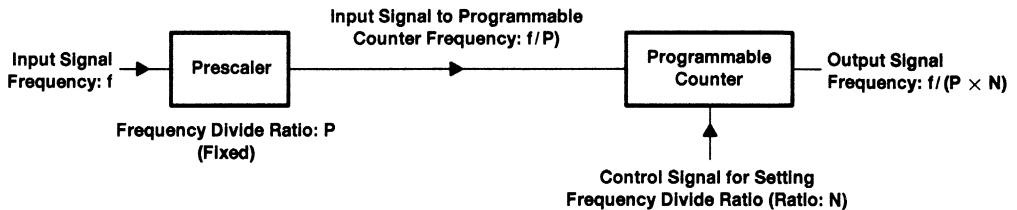


Figure 2–19. Prescaler Method

The prescaler frequency dividing ratio is fixed. As shown in Figure 2–19, if the prescaler frequency divide ratio is P and the programmable counter frequency dividing ratio is N , then the total frequency divide ratio becomes $P \times N$. As shown in Figure 2–20, if the frequency dividing ratios M and N of the programmable counters are changed, the VCO oscillating frequency is changed in steps of P/M times the phase-reference frequency. Thus the channel space (frequency resolution) becomes $f_{REF} \times P/M$. The PLL f_{REF} should be chosen to be M/P of the channel space. Thus, if f_{REF} is low, the loop-filter time parameters must be designed to be large with respect to f_{REF} ; however, the lock-up time can become too large for the application. Noise effects must be considered as well.

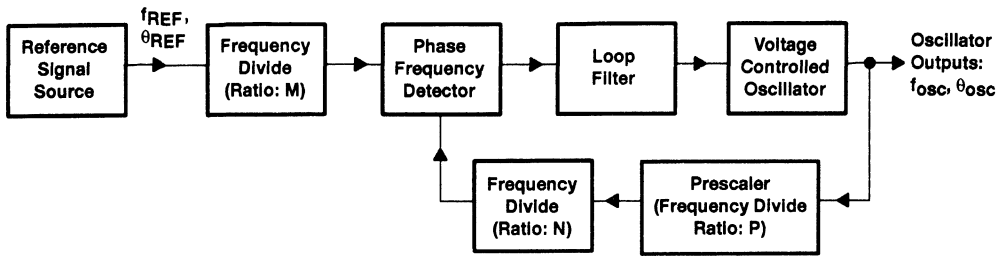


Figure 2–20. PLL Synthesizer Using Prescaler

2.8.2 Pulse Swallow Method (2s Modulus Prescaler Method)

When the channel space is equal to $1/M$ of the reference frequency, f_{REF} , the technique is called the pulse swallow method. This method uses a prescaler whose frequency divide ratio can be changed by a control signal as shown in Figure 2–21.

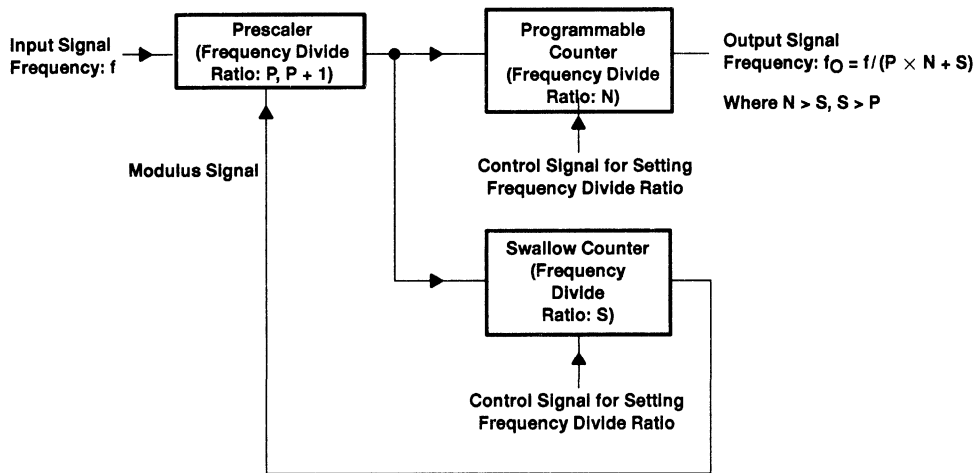


Figure 2–21. Pulse Swallow Method (2s Modulus Prescaler Method)

The prescaler frequency divide ratio is P or $P+1$. The counter consists of a programmable counter and a swallow counter which is used to control the prescaler. The frequency divide ratios are N and S respectively.

When the swallow counter is operating, the prescaler frequency divide ratio is $P+1$. The programmable counter and the swallow counter operate in parallel with the condition $N > S$. The swallow counter counts up to S and then generates a modulus signal to switch the prescaler. Then the prescaler's frequency divide ratio becomes P .

Thus, during the time period in which the swallow counter is dividing the frequency while counting up to S (time period S/N), the total frequency divide ratio is $(P+1) \times N$. During the remaining time period, $N-S$, in which the programmable counter divides the frequency [time period $(N-S)/N$], the total frequency divide ratio is $P \times N$. Now the output signal frequency can be expressed by the following equation:

$$f_o = f / (P \times N + S) \tag{2.38}$$

By examining the actual operation of the PLL shown in Figure 2–22 and equation 2.38, P is the coefficient for N but not for S . Thus, each time the value of S changes, the frequency only changes by f_{REF}/M . By using the pulse swallow method and a prescaler, a channel space of f_{REF}/M can be obtained.

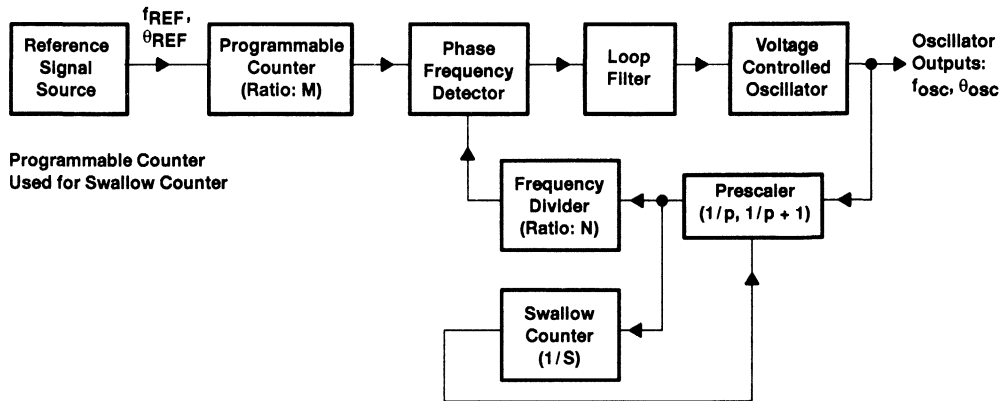


Figure 2–22. PLL Frequency Synthesizer Based on Pulse Swallow Method

Many variations exist by combining frequency dividers. A specific frequency divider technique can be adopted according to the application.

3 TLC2932IPW

3.1 Overview

The TLC2932IPW can be used for designing high performance PLLs and consists of a voltage controlled oscillator (VCO) operating at up to 50 MHz and an edge detection type phase frequency detector (PFD).

In the design of a PLL, the VCO lock range is determined by the value of a single external bias resistor. In addition, by using the inhibit function, the VCO can be turned off to reduce power dissipation. By switching the VCO output select terminal externally, the output frequency can be divided in half. Thus, lower frequencies can be produced and a 50% duty cycle can be achieved.

With the on-chip charge pump, the PFD detects the phase difference between the rising edges of an external input signal and a phase-reference signal from a reference signal source. Also the PFD output can be controlled externally by the input state to a high impedance output.

The design of a TLC2932IPW system, calculations of loop filters, layout considerations, and input-output protection circuits are explained in the following sections.

3.2 Voltage-Controlled Oscillator (VCO)

The TLC2932IPW VCO has the following special features:

- The VCO only requires one external bias resistor for oscillation and for setting the VCO variable oscillating frequency range. As shown in Figure 3–1, the possible lock frequency range is from 22 MHz to 50 MHz. The range of possible settings for bias resistance is 1.5 k Ω to 3.3 k Ω .

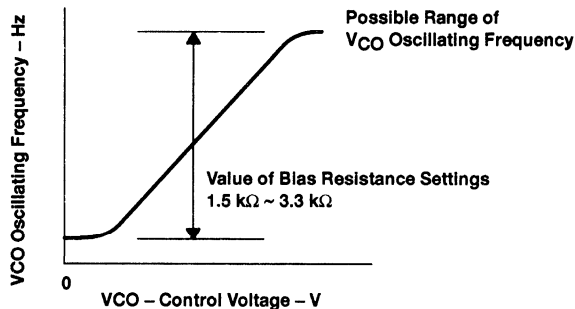


Figure 3–1. Setting the VCO Oscillating Frequency

- By switching the VCO select terminal externally, the output frequency can be divided in half to produce a lower frequency; moreover, a duty cycle of 50% is possible. By using this function, the possible frequency range is extended to 11 MHz. Video applications at 14.31818 MHz are possible.
- TLC2932IPW VCO has an inhibit function that is controlled externally
 - the output waveform can be initialized
 - power dissipation during power down can be reduced

For detailed specifications, refer to the TLC2932 data sheet.

3.3 Phase Frequency Detector (PFD)

TLC2932IPW PFD has the following special features:

- The PFD is a high speed edge triggered type with charge pump. As shown in Figure 3–2, the difference between the rising edges of two input signal frequencies can be detected.
- Depending on the external controller, the PFD output
 - can be placed in a high impedance state
 - is static when put in the power down mode

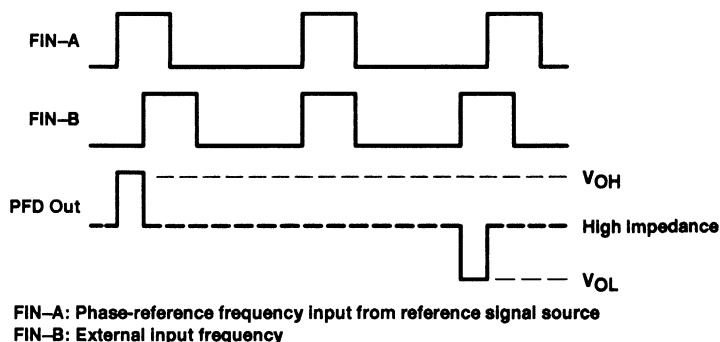


Figure 3–2. Timing of PFD Operation

3.4 Loop Filter

The loop filter design shown is based on the design equations for loop filter parameters derived in Sections 2.5. and 2.6. Figure 3.3 shows a design based on the block diagram of a PLL synthesizer using the prescaler method.

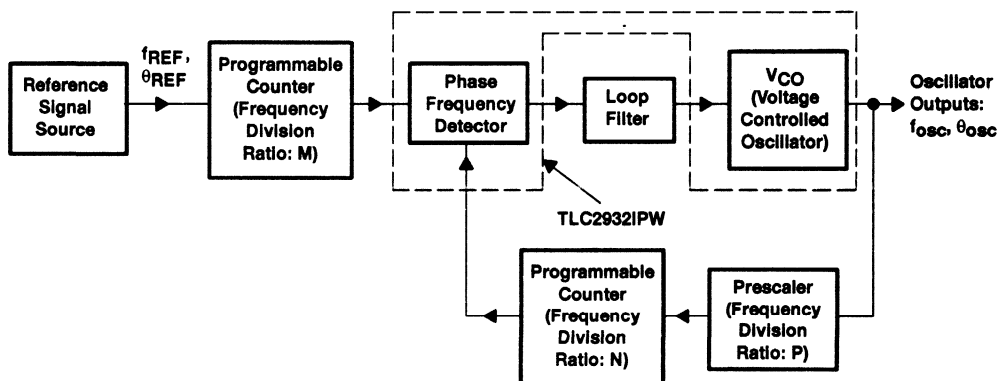


Figure 3–3. Block Diagram of PLL Synthesizer Using the Prescaler Method

3.5 Setting System Parameters

3.5.1 Setting the Phase Reference Frequency and Output Frequency from a Reference Signal Source

Each frequency is set to the values shown in Table 3–1. A 14.31818 MHz crystal is used as the reference signal source. This frequency is divided by 910 so that it can be used as the phase reference frequency. Then, the VCO output signal is 14.31818 MHz.

Table 3–1. Frequency Settings

REFERENCE SIGNAL SOURCE	SYMBOL	VALUE	UNIT
Oscillating frequency	f_{REF}	14.31818	MHz
Phase reference frequency	f_{ref}/M	14.31818/910	MHz
Output frequency	f_{osc}	14.31818	MHz

3.5.2 Setting the Frequency Division Ratios of the Programmable Counter and Prescaler

Using the settings in Table 3–1, the frequency division ratios of the programmable counter and prescaler can be determined. However, this time the design proceeds based on the settings in Table 3–2. In practice, the frequency division ratio for the prescaler is based on the frequency operating range of the programmable counter input signal.

Table 3–2. Settings for Frequency Division Ratios of the Programmable Counters and Prescaler

NAME	PARAMETER	VALUE
Programmable counter (Phase reference frequency side)	M	910
Programmable counter	N	455
Prescaler	P	2

Therefore, the total frequency division ratio becomes $P \times N = 910$.

3.5.3 Setting the Lock-Up Time

The required lock-up time is 2 ms which is the time it takes for the phase to lock and is dependent on system requirements.

3.5.4 Determining the Damping factor, ζ

The damping factor, ζ , is chosen to be 0.7.

3.5.5 Calculating the PLL Natural Angular Frequency, ω_n

For $\zeta = 0.7$ and from equation 2.34, ω_n is calculated to be

$$\omega_n = \frac{\omega_n \tau}{t} = \frac{4.5}{2 \times 10^{-3}} = 2250 \text{ (rad/sec)}$$

3.5.6 Calculating VCO Gain, K_V

Figure 3–4 shows an example of the oscillating frequency characteristic of the TLC2932 internal VCO. The VCO gain is calculated from a characteristic curve in the data sheet. By switching the SELECT terminal, the output frequency is divided in half and the resulting characteristic curve is shown in Figure 3–4.

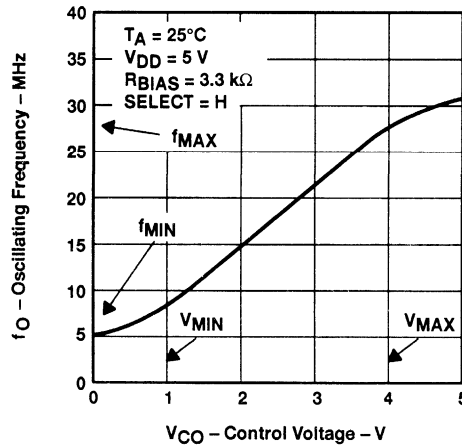


Figure 3–4. VCO Oscillating Frequency Characteristic

The VCO gain, K_V , from equation 2.35 is

$$K_V = \frac{f_{MAX} - f_{MIN}}{V_{MAX} - V_{MIN}} \times 2\pi = \frac{(27.5 - 7) \times 10^6}{4 - 1} \times 2\pi \cong 41 \times 10^6 \text{ [rad/sec/V]} \quad (3.1)$$

3.5.7 Calculating PFD Gain, K_θ

The PFD output characteristic is shown in Figure 2–15. By substituting the values obtained from the data sheet into equation 2.36, the PFD gain is calculated to be

$$K_\theta \cong 0.34 \text{ [V/rad]} \quad (3.2)$$

The design and circuit specifications mentioned above are listed in Tables 3–3 and 3–4.

Table 3–3. PLL Design Specifications

DESIGN SPECIFICATIONS			
NAME	SYMBOL	VALUE	UNIT
PLL damping factor	ζ	0.7	
Radian value to selected lock-up time	$\omega_n t$	4.5	rad
Lock-up time	t	0.002	s
Desired output frequency	f_{osc}	14.318180	MHz
Phase reference frequency	f_{REF}	15734.26374	Hz

Table 3–4. PLL Circuit Specifications (SELECT Terminal = H Level)

CIRCUIT SPECIFICATIONS ($V_{DD} = 5\text{ V}$, $R_{BIAS} = 3.3\text{ k}\Omega$, $T_A = 25^\circ\text{C}$)			
NAME	SYMBOL	VALUE	UNIT
VCO frequency range	f_{MAX}	27	MHz
	f_{MIN}	7.5	
VCO control voltage range	V_{MAX}	4	V
	V_{MIN}	1	
Phase detector output level	V_{OH}	4.5	V
	V_{OL}	0.2	
Phase detector range of detection		12.56	rad
Frequency divide ratio	N	910	
PLL natural angular frequency	ω_n	2250	rad/sec

3.5.8 Lag-Lead Filter Case

From the design and circuit specifications above and using the lag-lead filter of Figure 2–16, C2 is selected to be 1/10 of the C1 value.

The calculations are shown in Table 3–5. The transfer function gain characteristics and phase characteristics are shown in Figure 3–5 and the step response is shown in Figure 3–6.

Table 3–5. Calculation Example of Lag-Lead Filter Parameters

LAG-LEAD FILTER		
PARAMETER	VALUE	UNIT
C1	1.00E–06	F
R1	2476	Ω
R2	557	Ω
C2	1.00E–07	F

Where $C2 = C1 \times 1/10$

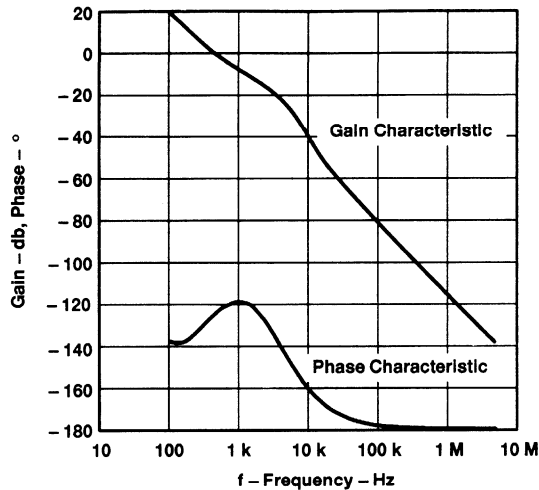


Figure 3-5. PLL Transfer Function Gain Characteristics and Phase Characteristics (Lag-Lead Filter used as Loop Filter)

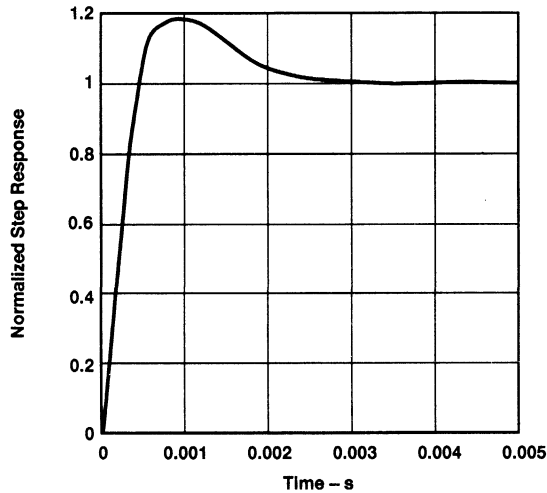


Figure 3-6. PLL Step Response Characteristic (Lag-Lead Filter used as Loop Filter)

3.5.9 Active Filter Case

The active filter is shown in Figure 2-17. Each parameter can be calculated using equations 2.32 and 2.33. C_2 is calculated from equation 2.37 in Section 2.7.

Table 3-6 shows an example of these calculations. Figure 3-7 shows the transfer function gain characteristics and phase characteristics of a PLL using the filter parameters in Table 3-6. Figure 3-8 shows the step response of utilizing the filter parameters in Table 3-6.

Table 3–6. Calculation Example of Active Filter Parameters

ACTIVE FILTER		
PARAMETER	VALUE	UNIT
C1	1.00E-06	F
R1	3033	Ω
R2	622	Ω
C2	7.14E-07	F

Where $C2 = R2/10 \omega_n$

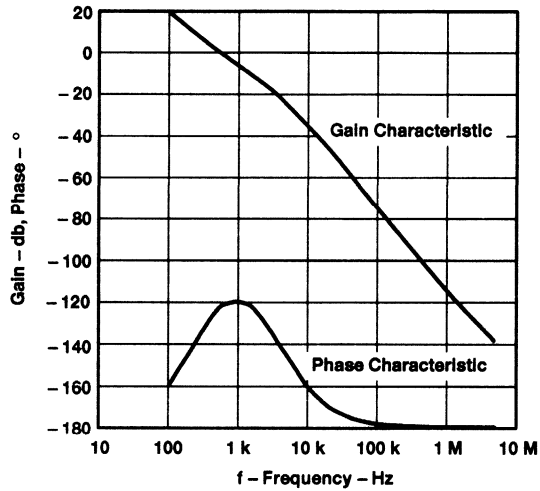


Figure 3–7. PLL Transfer Function Gain Characteristics and Phase Characteristics (Active Filter used as Loop Filter)

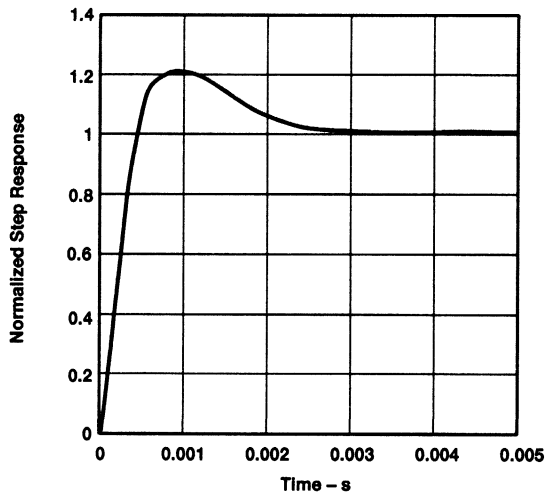


Figure 3–8. PLL Step Response Characteristic (Active Filter used as Loop Filter)

A basic design example for a PLL loop filter is somewhat of an ideal case. In practice, the PLL characteristics greatly depend on the evaluation board used and the layout of components in the system. Consequently, it is necessary to plan the evaluation board and system carefully.

Section 4, contains the evaluation results of the loop filters.

3.6 Layout Considerations

When designing an evaluation or production board, the following precautions, based on techniques used with high frequency analog circuits must be exercised.

- Depending on the IC socket used, increased circuit resistance, inductance, and capacitance can degrade the performance in some cases. If possible, do not use IC sockets. Direct connection to the board is recommended.
- Extreme care should be exercised with wiring and connections. Casual wiring should be avoided.
- Power supplied to the V_{DD} terminal of the VCO should be separated from the digital portion. Moreover, by inserting high pass capacitors, noise coupling can be avoided as much as possible.
- It is necessary to consider the VCO ground terminal. The analog portion and digital portion must be separated. The analog portion should be connected to a ground plane. The design should avoid the coupling of switching noise from the digital portion.
- The loop filter ground should be connected to analog ground.
- External components (such as the loop filter and high pass capacitors) should be placed as close as possible to the IC.

Layouts and bread boards must be carefully designed to realize the full potential of the TLC2932. These techniques must be used to ensure proper operation of the PLL design.

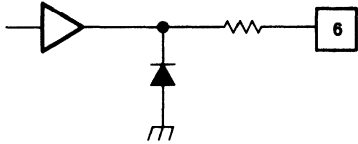
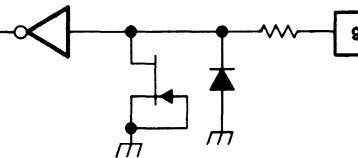
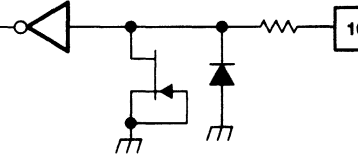
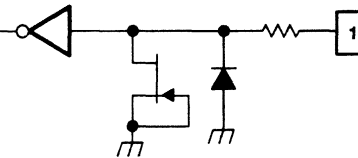
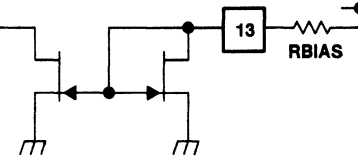
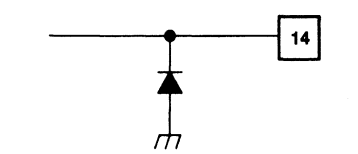
3.7 Input-Output Protection Circuits

The input and output protection circuits are shown in Table 3–7.

Table 3–7. Input-Output Protection Circuits

TERMINAL NAME	NO.	CIRCUIT	FUNCTION
LOGIC V_{DD}	1		Voltage supply terminal for internal logic. It is desirable to separate completely from the VCO voltage supply terminal.
SELECT	2		VCO output frequency 1/2 divider select terminal. By controlling this terminal using external logic, the VCO output frequency can be divided in half.
VCO OUT	3		VCO output terminal. During inhibit, this terminal is taken low.
FIN-A,B	4, 5		The two input terminals used for detecting the edge difference of reference frequency, f_{ref-IN} , and external counter's frequency. Usually f_{ref-IN} is connected to the FIN-A terminal and the external counter output frequency is connected to the FIN-B terminal.

Table 3-7. Input-Output Protection Circuits (Continued)

TERMINAL NAME NO.	CIRCUIT	FUNCTION
PFD OUT 6		The PFD output terminal can be put in high impedance state.
LOGIC GND 7		Internal logic ground terminal.
NC 8		Not connected internally.
PFD INHIBIT 9		The PFD inhibit function control terminal.
VCO INHIBIT 10		The VCO inhibit function control pin
VCO GND 11		VCO ground terminal
VCO IN 12		The VCO control voltage input terminal usually connected to VCO control voltage from the external loop filter of PLL.
R BIAS 13		The terminal for connecting the bias resistor for setting the VCO oscillating frequency. To provide a bias for the operation of internal VCO and for frequency setting and tuning, a bias resistor is connected between this terminal and the power supply line.
VCO V _{DD} 14		This terminal supplies the supply voltage to the VCO. It is desirable to completely separate this from the logic power terminal.

4 APPLICATION EXAMPLE

4.1 Introduction

An evaluation example using the TLC2932IPW in a PLL application is described in the following sections.

4.2 National Television System Committee (NTSC) Method 4 Frequency Sub-Carrier (fsc), 8 fsc Output Signal Evaluation

Table 4-1 shows that by combining a phase reference frequency and loop filter, the NTSC method of 4 fsc and 8 fsc output signals can be generated.

The block diagram is shown in Figure 4-1. Figure 4-2 shows the circuit for evaluation, using a passive lag-lead filter as the loop filter. This evaluation circuit is based on the conditions stated in number 2 of Table 4-1.

When an active filter is used, because of additional inversion added to the loop, the phase frequency detector input signal is reversed from that in the passive lag-lead filter case.

Table 4-1. Evaluation Conditions ($V_{DD} = 5\text{ V}$, $T_A = 25^\circ\text{C}$, $R_{BIAS} = 3.3\text{ k}\Omega$)

NO.	PHASE REFERENCE FREQUENCY	OUTPUT FREQUENCY	LOOP FILTER	EVALUATION RESULT
1	fsc (NTSC) = 3.579545 MHz	4 fsc (NTSC) = 14.31818 MHz	Lag-lead and active	Section 4.3
2	HD (NTSC) = 4 fsc/910 \approx 15.7 kHz	4 fsc (NTSC) = 14.31818 MHz		Section 4.6
3	HD (NTSC) = 4 fsc/910 \approx 15.7 kHz	8 fsc = 28.63636 MHz		Section 4.9

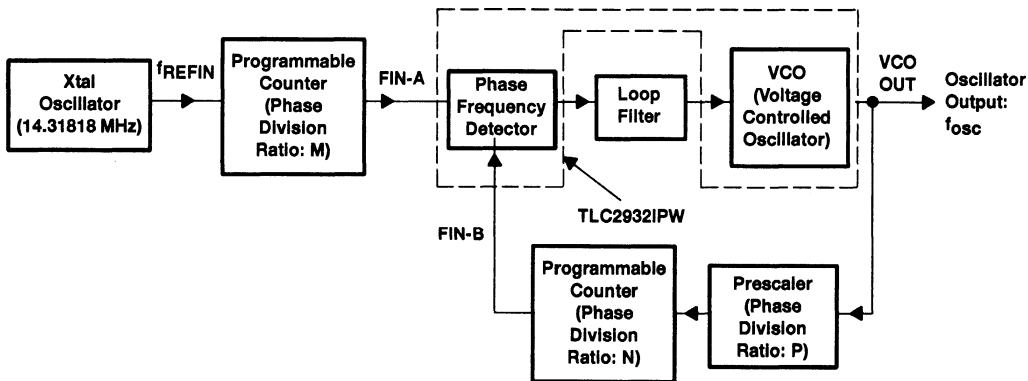


Figure 4-1. 4 fsc Output Evaluation Block Diagram

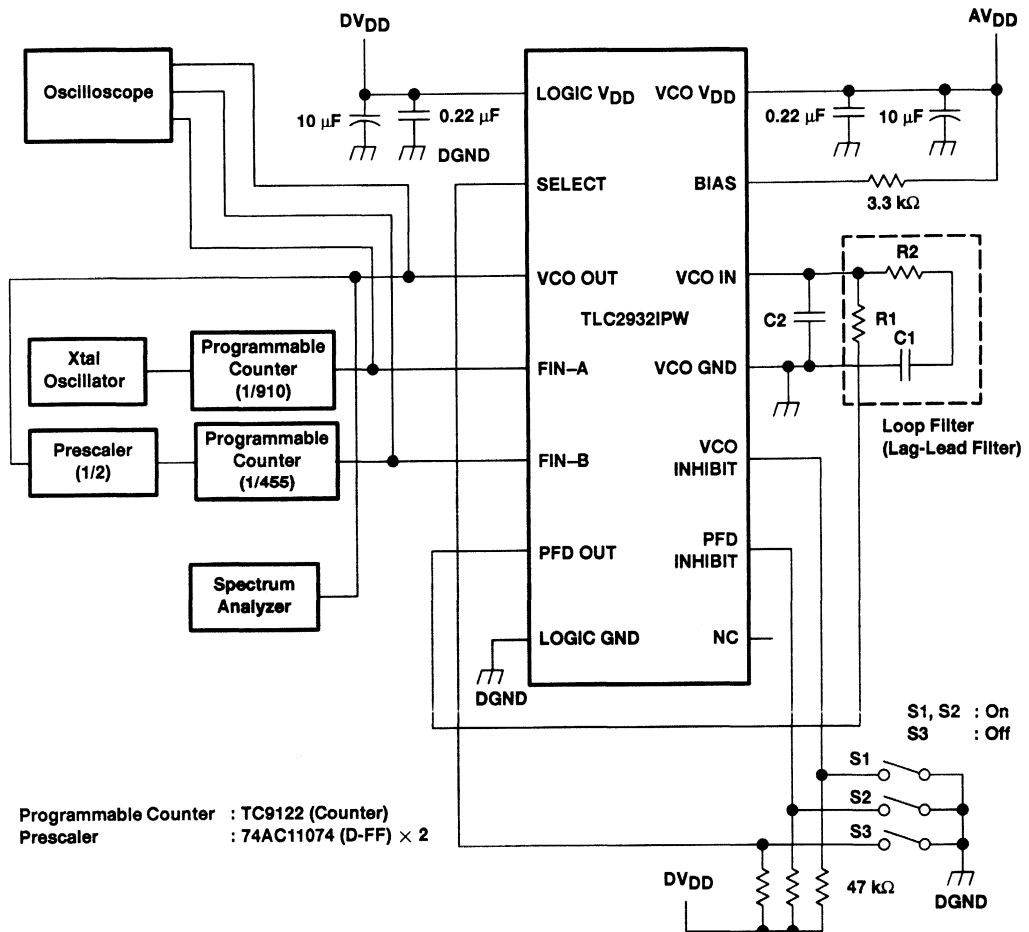


Figure 4-2. Evaluation Circuit (Based on Number 2 of Table 4-1) (Lag-Lead Filter Used as Loop Filter)

4.3 Evaluation Results (Phase Reference Frequency = fsc, Output Frequency = 4 fsc)

In this evaluation, the fsc (3.579545 MHz) shown as number 1 in Table 4-1, is used as the phase reference frequency to generate a 4 fsc (14.31818 MHz) output frequency. The details and results for the cases of using a lag-lead filter and an active filter as the loop filter are described in the following sections.

4.3.1 Programmable Counter and Prescaler Frequency Division Ratio Settings

Based on the evaluation block diagram of Figure 4-1, the frequency division ratio settings for the programmable counters and prescaler are listed in Table 4-2.

Table 4-2. Frequency Division Ratio Settings

FREQUENCY DIVISION RATIO	M	P	N	P × N
Frequency divide value	4	1	4	4

4.3.2 Loop Filter Parameter Settings

From the loop filter design procedures of Sections 2.5 and 2.6, the setting of each parameter is listed in Table 4–3.

Table 4–3. Loop Filter Parameter Settings

LOOP FILTER TYPE	C1	R1	R2	C2	CIRCUIT CONSTRUCTION
Lag-lead filter	1 μ F	1.6 k Ω	36 Ω	0.1 μ F	Figure 2–16
Active filter	1 μ F	1.6 k Ω	36 Ω	0.1 μ F	Figure 2–17

NOTE: The numerical values in Table 4–3 are the capacitance and resistance closest to the calculated values.

4.3.3 Passive Lag-Lead Filter Used as a Loop Filter

The evaluation results of using a lag-lead filter as the loop filter are illustrated in Figure 4–3 and Figure 4–4. Figure 4–3 shows the individual waveforms as observed from an oscilloscope. Figure 4–4 shows the output signal measured by a spectrum analyzer.

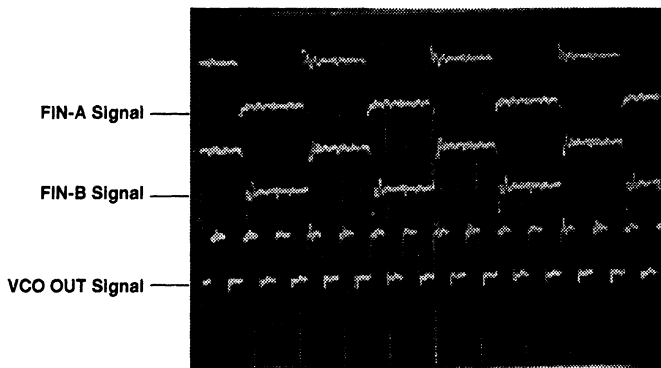


Figure 4–3. Waveforms Using Passive Lag-Lead Filter (100 ns/div on horizontal axis)

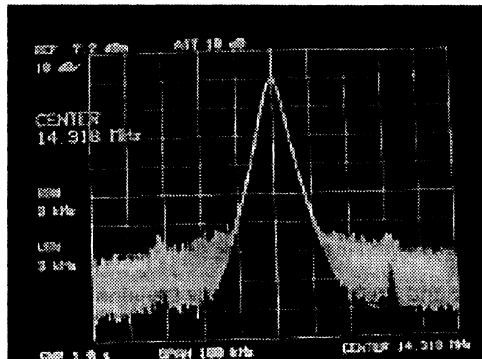
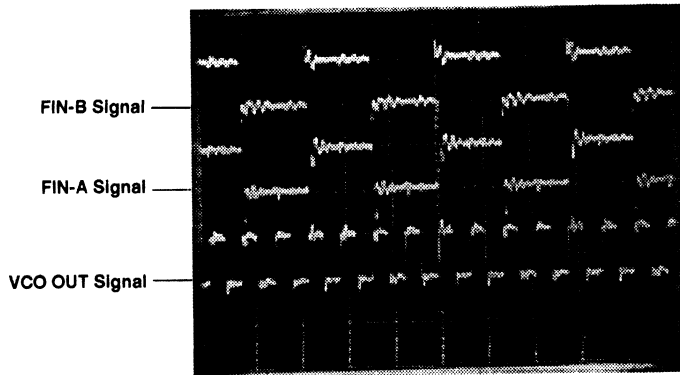


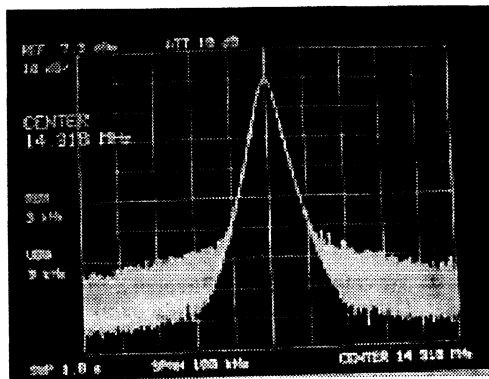
Figure 4–4. Spectrum of the VCO Output Signal When Using a Passive Lag-Lead Filter (100 kHz/div on horizontal axis)

4.3.4 Active Filter Used as a Loop Filter

The evaluation results of using an active filter as the loop filter are illustrated in Figure 4–5 and Figure 4–6. Figure 4–5 shows the individual waveforms as observed from an oscilloscope. Figure 4–6 shows the output signal measured by a spectrum analyzer.



**Figure 4-5 Waveforms Using Active Filter
(100 ns/div on horizontal axis)**



**Figure 4-6. Spectrum of the VCO Output Signal When Using an Active Filter
(100 kHz/div on horizontal axis)**

4.4 Evaluation Results (Phase Reference Frequency = 4 fsc/910, Output Frequency = 4 fsc)

In this evaluation of number 2 in Table 4-1, fsc/910 (15.7 kHz) is used as the phase reference frequency to generate a 4 fsc (14.31818 MHz) output frequency. The details and results for the cases of using a lag-lead filter and an active filter as the loop filter are described in the following sections.

4.4.1 Programmable Counter and Prescaler Frequency Division Ratio Settings

Based on the evaluation block diagram of Figure 4-1, the frequency division ratio settings for the programmable counter and prescaler are listed in Table 4-4.

Table 4-4. Frequency Division Ratio Settings

FREQUENCY DIVISION RATIO	M	P	N	P × N
Frequency divide value	910	2	455	910

4.4.2 Loop Filter Settings

Following the loop filter design procedures of Sections 2.5 and 2.6, the setting of each parameter is listed in Table 4-5.

Table 4–5. Loop Filter Parameter Settings

LOOP FILTER	C1	R1	R2	C2	CIRCUIT CONSTRUCTION
Lag-lead filter	1 μF	2.4 $\text{k}\Omega$	560 Ω	0.1 μF	Figure 2–16
Active filter	1 μF	3 $\text{k}\Omega$	620 Ω	0.1 μF	Figure 2–17

NOTE: Numerical values in Table 4–5 are the capacitance and resistance closest to the calculated values.

4.4.3 Passive Lag-Lead Filter Used as a Loop Filter

Using lag-lead filter as the loop filter, the evaluation results are illustrated in Figure 4–7 and Figure 4–8. Figure 4–7 shows the individual waveforms as observed from an oscilloscope. Figure 4–8 shows the output signal measured by a spectrum analyzer.

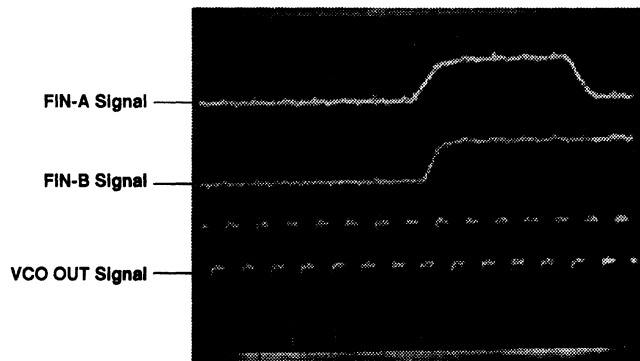


Figure 4–7. Waveforms Using Passive Lag-Lead Filter (100 ns/div on horizontal axis)

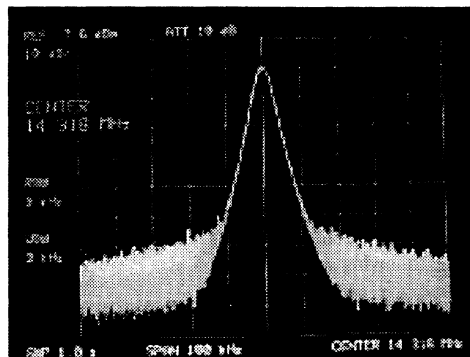


Figure 4–8. Spectrum of the VCO Output Signal When Using a Passive Lag-Lead Filter (100 kHz/div on horizontal axis)

4.4.4 Active Filter Used as a Loop Filter

Using an active filter as the loop filter, the evaluation results are illustrated in Figure 4–9 and Figure 4–10. Figure 4–9 shows the individual waveforms as observed from an oscilloscope. Figure 4–10 shows the output signal measured by a spectrum analyzer.

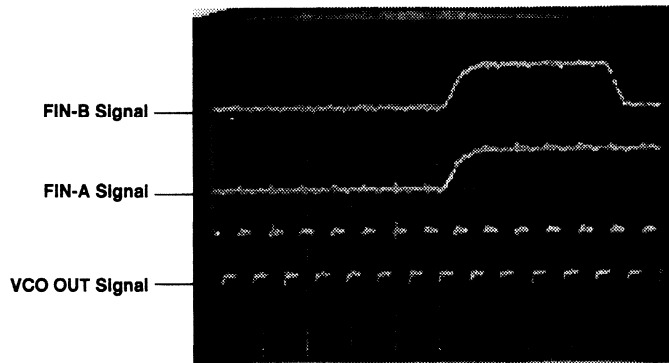


Figure 4-9. Waveforms Using Active Filter (100 ns/div on horizontal axis)

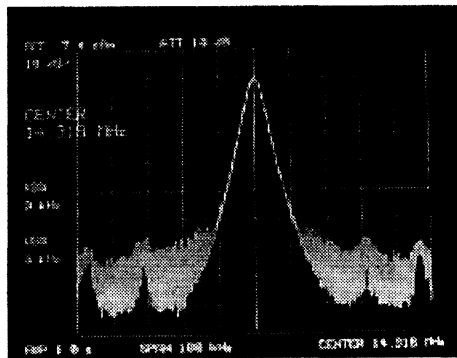


Figure 4-10. Spectrum of the VCO Output Signal When Using an Active Filter (100 kHz/div on horizontal axis)

4.5 Evaluation Results (Phase Reference Frequency = $f_{sc}/910$, Output Frequency = 8 fsc)

In this evaluation of number 1 in Table 4-1, f_{sc} (3.579545 kHz) is used as the phase reference frequency to generate a 8 fsc (2×14.31818 MHz) output frequency. The details and results for the cases of using a lag-lead filter and an active filter as the loop filter are described in the following sections.

4.5.1 Programmable Counter and Prescaler Frequency Division Ratio Settings

Based on the evaluation block diagram of Figure 4-1, the frequency division settings for programmable counters and prescaler are listed in Table 4-6.

Table 4-6. Frequency Division Ratio Settings

FREQUENCY DIVIDE RATIO	M	P	N	P × N
Frequency dividing value	910	4	455	1820

4.5.2 Loop Filter Settings

Following the loop filter design procedures of Sections 2.5 and 2.6, the setting of each parameter is listed in Table 4-7.

Table 4-7. Loop Filter Parameter Settings

LOOP FILTER	C1	R1	R2	C2	CIRCUIT CONSTRUCTION
Lag-lead filter	1 μ F	2.4 k Ω	560 Ω	0.1 μ F	Figure 2-16
Active Filter	1 μ F	3 k Ω	620 Ω	0.1 μ F	Figure 2-17

NOTE: Numerical values in Table 4-6 are the capacitance and resistance closest to the calculated values.

4.5.3 Passive Lag-Lead Filter Used as a Loop Filter

The evaluation results of using a lag-lead filter as the loop filter are illustrated in Figure 4-11 and Figure 4-12. Figure 4-11 shows the individual waveforms as observed from an oscilloscope. Figure 4-12 shows the output signal measured by a spectrum analyzer.

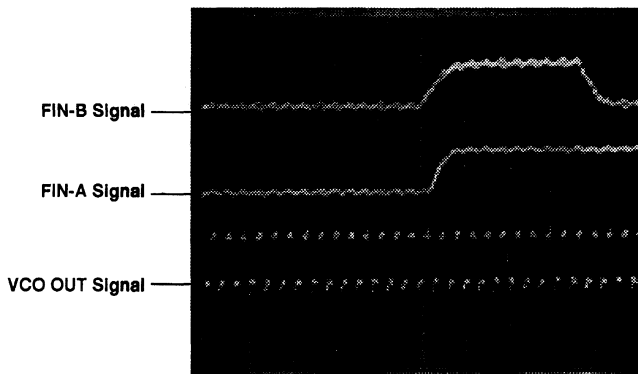


Figure 4-11. Waveforms Using Passive Lag-Lead Filter (100 ns/div on horizontal axis)

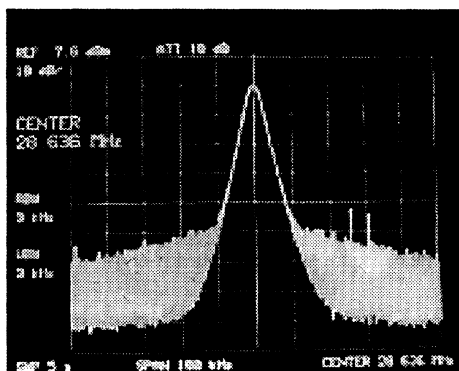
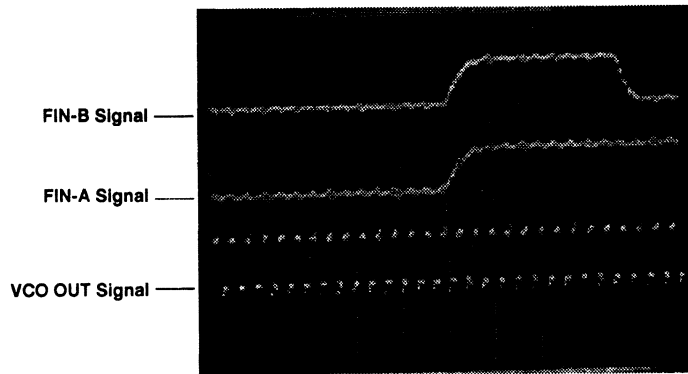


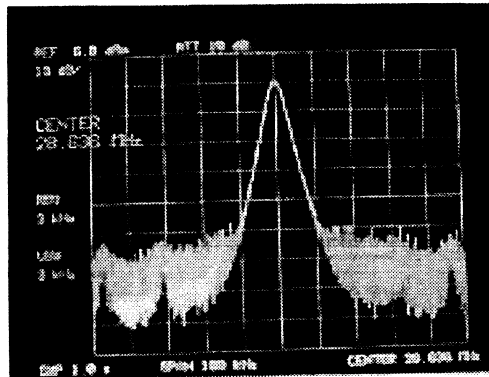
Figure 4-12. Spectrum of the VCO Output Signal When Using a Passive Lag-Lead Filter (100 kHz/div on horizontal axis)

4.5.4 Active Filter Used as a Loop Filter

The evaluation results of using an active filter as the loop filter are illustrated in Figure 4-13 and Figure 4-14. Figure 4-13 shows the individual waveforms as observed from an oscilloscope. Figure 4-14 shows the output signal measured by a spectrum analyzer.



**Figure 4–13. Waveforms Using an Active Filter
(100 ns/div on horizontal axis)**



**Figure 4–14. Spectrum of the VCO Output Signal When Using an Active Filter
(100 kHz/div on horizontal axis)**

4.6 Summary

The evaluation results shown were with the practical resistance and practical capacitance values closest to the calculated values used for the loop filter. The evaluations were carried out with a TLC2932IPW placed in the IC socket on an evaluation board with power supplies, and the BIAS terminal was bypassed directly on the bottom of the socket.

Better results can be achieved however by placing the TLC2932IPW directly on the evaluation board.

4.7 Examples of a PLL Application

The following sections contain PLL application examples.

4.7.1 Generating a 4 fsc NTSC Signal from a NTSC Signal

A NTSC signal horizontal synchronization frequency (f_H) is multiplied by 910 to generate a 4 fsc NTSC signal. Figure 4–15 shows a block diagram of the PLL.

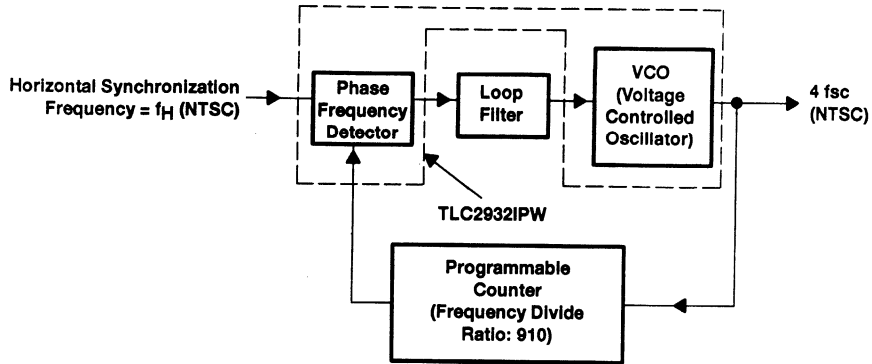


Figure 4–15. Generating a 4 fsc (NTSC) Signal by Multiplying the Horizontal Synchronization Frequency

4.7.2 Generating a 4 fsc PAL Signal from a PAL Signal

A phase alteration line (PAL) signal horizontal synchronization frequency (f_H) is multiplied by 910 to generate a 4 fsc PAL signal. Figure 4–16 shows a block diagram of the PLL.

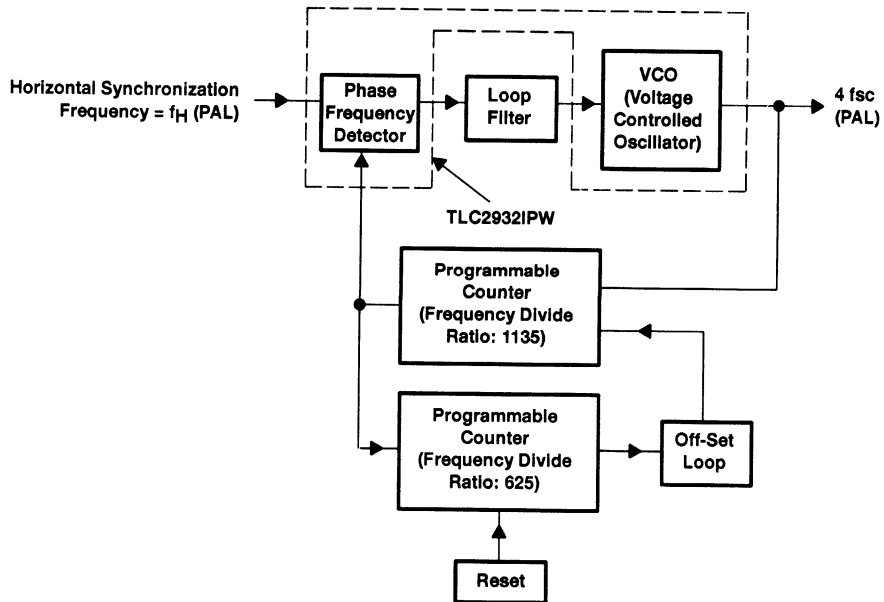


Figure 4–16. Generating a 4 fsc (PAL) Signal by Multiplying the Horizontal Synchronization Frequency

4.7.3 Generating a 13.5 MHz Output from a NTSC or PAL Signal

Figure 4-17 shows the derivative of a 4 fsc signal from a PAL or NTSC horizontal synchronization frequency.

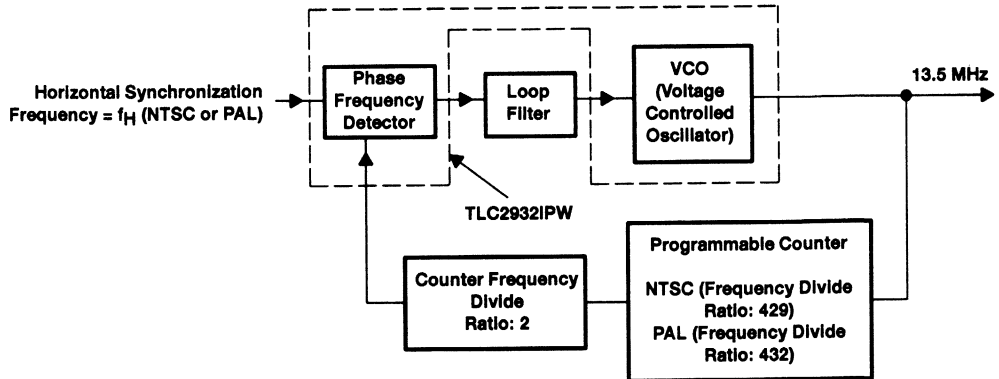


Figure 4-17. Multiplying the Horizontal Synchronization Frequency of a NTSC Signal or PAL Signal to Generate a 13.5 MHz Output

Understanding Data Converters

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1 INTRODUCTION

This application report discusses the way the specifications for a data converter are defined on a manufacturer's data sheet and considers some of the aspects of designing with data conversion products. It covers the sources of error that change the characteristics of the device from an ideal function to reality.

2 THE IDEAL TRANSFER FUNCTION

The theoretical ideal transfer function for an ADC is a straight line, however, the practical ideal transfer function is a uniform staircase characteristic shown in Figure 1. The DAC theoretical ideal transfer function would also be a straight line with an infinite number of steps but practically it is a series of points that fall on the ideal straight line as shown in Figure 2.

2.1 Analog-to-Digital Converter (ADC)

An ideal ADC uniquely represents all analog inputs within a certain range by a limited number of digital output codes. The diagram in Figure 1 shows that each digital code represents a fraction of the total analog input range. Since the analog scale is continuous, while the digital codes are discrete, there is a quantization process that introduces an error. As the number of discrete codes increases, the corresponding step width gets smaller and the transfer function approaches an ideal straight line. The steps are designed to have transitions such that the midpoint of each step corresponds to the point on this ideal line.

The width of one step is defined as 1 LSB (one least significant bit) and this is often used as the reference unit for other quantities in the specification. It is also a measure of the resolution of the converter since it defines the number of divisions or units of the full analog range. Hence, 1/2 LSB represents an analog quantity equal to one half of the analog resolution.

The resolution of an ADC is usually expressed as the number of bits in its digital output code. For example, an ADC with an n-bit resolution has 2^n possible digital codes which define 2^n step levels. However, since the first (zero) step and the last step are only one half of a full width, the full-scale range (FSR) is divided into $2^n - 1$ step widths.

Hence

$$1 \text{ LSB} = \text{FSR} / (2^n - 1) \text{ for an } n\text{-bit converter}$$

CONVERSION CODE	
RANGE OF ANALOG INPUT VALUES	DIGITAL OUTPUT CODE
4.5 • 5.5	0 ... 101
3.5 • 4.5	0 ... 100
2.5 • 3.5	0 ... 011
1.5 • 2.5	0 ... 010
0.5 • 1.5	0 ... 001
0 • 0.5	0 ... 000

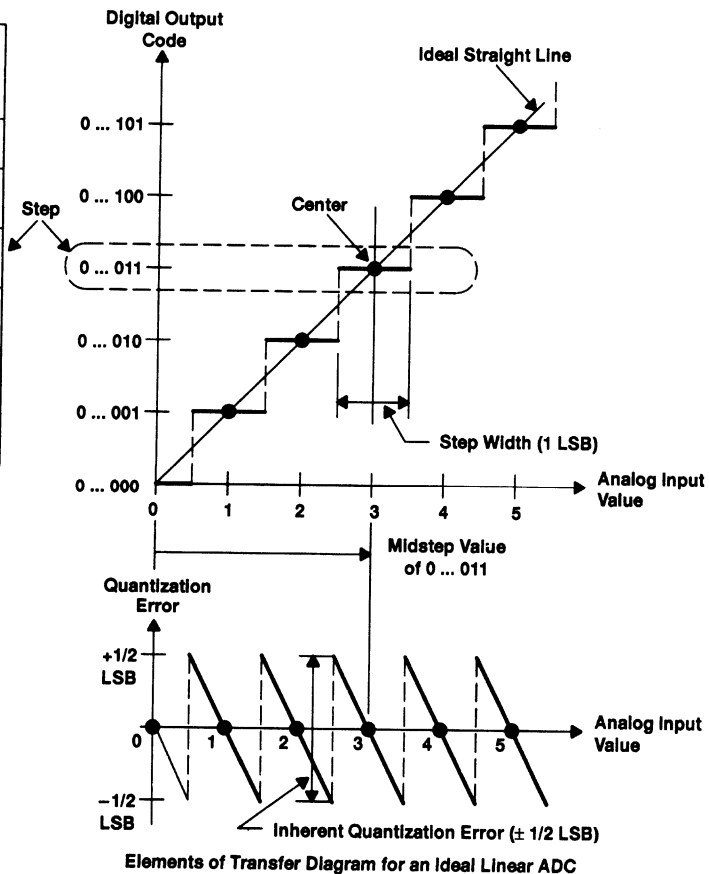
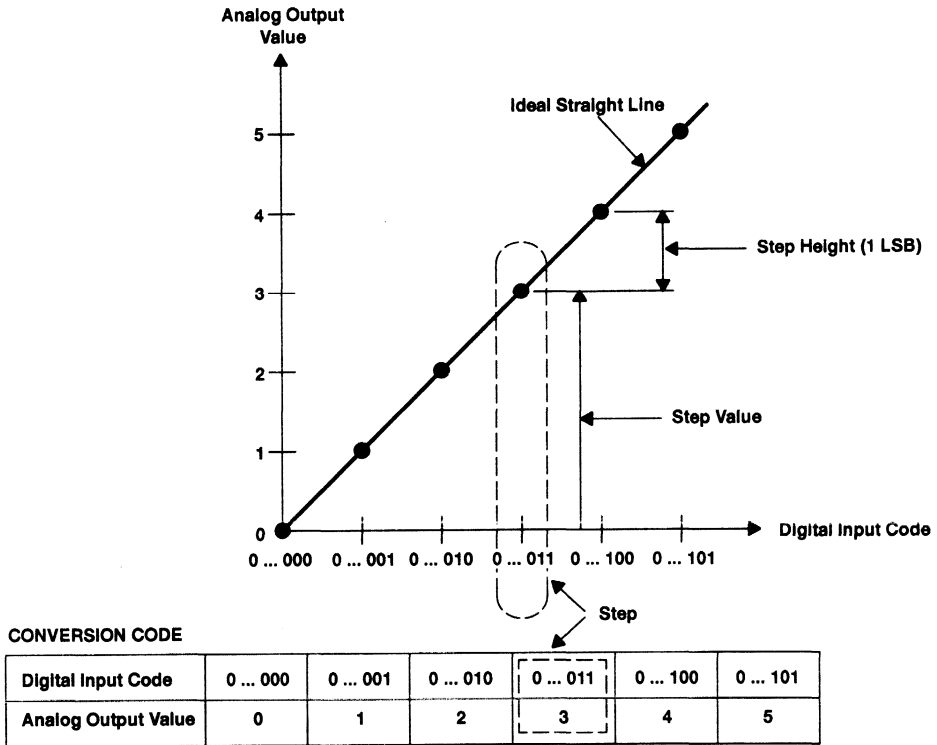


Figure 1. The Ideal Transfer Function (ADC)

2.2 Digital-to-Analog Converter (DAC)

A DAC represents a limited number of discrete digital input codes by a corresponding number of discrete analog output values. Therefore, the transfer function of a DAC is a series of discrete points as shown in Figure 2. For a DAC, 1 LSB corresponds to the height of a step between successive analog outputs, with the value defined in the same way as for the ADC. A DAC can be thought of as a digitally controlled potentiometer whose output is a fraction of the full scale analog voltage determined by the digital input code.



Elements of Transfer Diagram for an Ideal Linear DAC

Figure 2. The Ideal Transfer Function (DAC)

3 SOURCES OF STATIC ERROR

Static errors, that is those errors that affect the accuracy of the converter when it is converting static (dc) signals, can be completely described by just four terms. These are offset error, gain error, integral nonlinearity and differential nonlinearity. Each can be expressed in LSB units or sometimes as a percentage of the FSR. For example, an error of 1/2 LSB for an 8-bit converter corresponds to 0.2% FSR.

3.1 Offset Error

The offset error as shown in Figure 3 is defined as the difference between the nominal and actual offset points. For an ADC, the offset point is the midstep value when the digital output is zero, and for a DAC it is the step value when the digital input is zero. This error affects all codes by the same amount and can usually be compensated for by a trimming process. If trimming is not possible, this error is referred to as the zero-scale error.

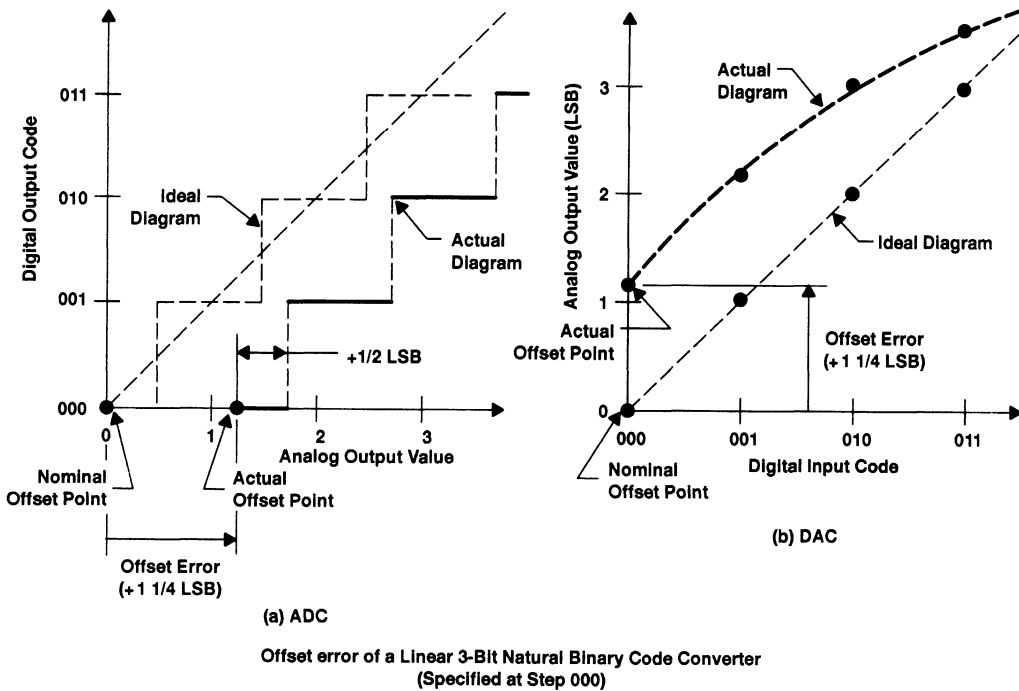
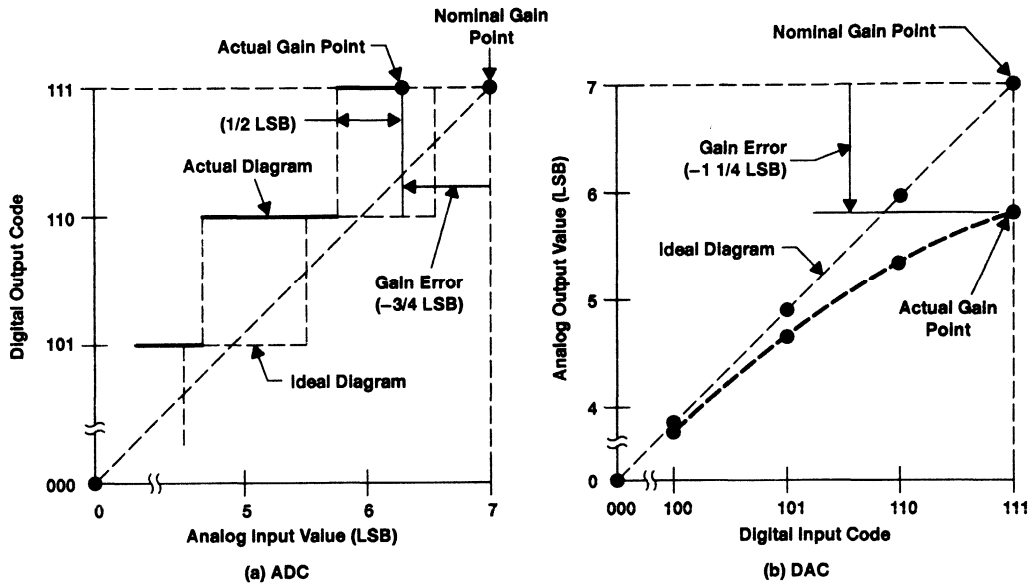


Figure 3. Offset Error

3.2 Gain Error

The gain error shown in Figure 4 is defined as the difference between the nominal gain points on the transfer function after the offset error has been corrected to zero. For an ADC, the gain point is the midstep value when the digital output is full scale, and for a DAC it is the step value when the digital input is full scale. This error represents a difference in the slope of the actual and ideal transfer functions and as such corresponds to the same percentage error in each step. This error can also usually be adjusted to zero by trimming.

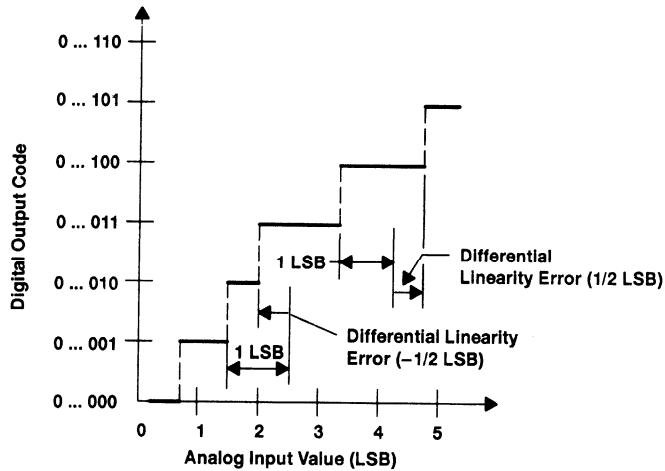


Gain Error of a Linear 3-Bit Natural Binary Code Converter (Specified at Step 111), After Correction of the Offset Error

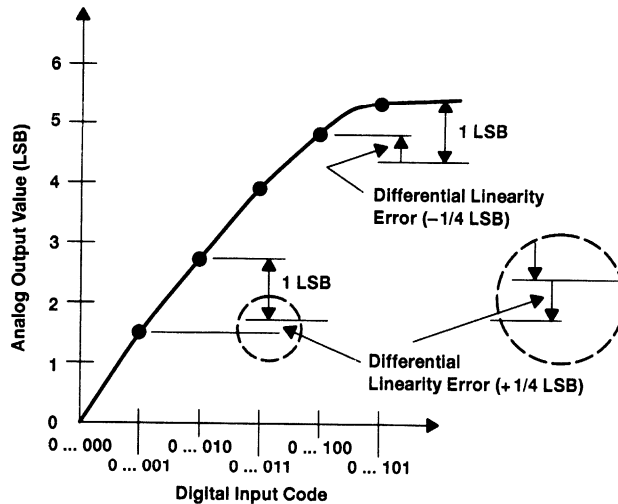
Figure 4. Gain Error

3.3 Differential Nonlinearity (DNL) Error

The differential nonlinearity error shown in Figure 5 (sometimes seen as simply differential linearity) is the difference between an actual step width (for an ADC) or step height (for a DAC) and the ideal value of 1 LSB. Therefore if the step width or height is exactly 1 LSB, then the differential nonlinearity error is zero. If the DNL exceeds 1 LSB, there is a possibility that the converter can become nonmonotonic. This means that the magnitude of the output gets smaller for an increase in the magnitude of the input. In an ADC there is also a possibility that there can be missing codes i.e., one or more of the possible 2^n binary codes are never output.



(a) ADC



(b) DAC

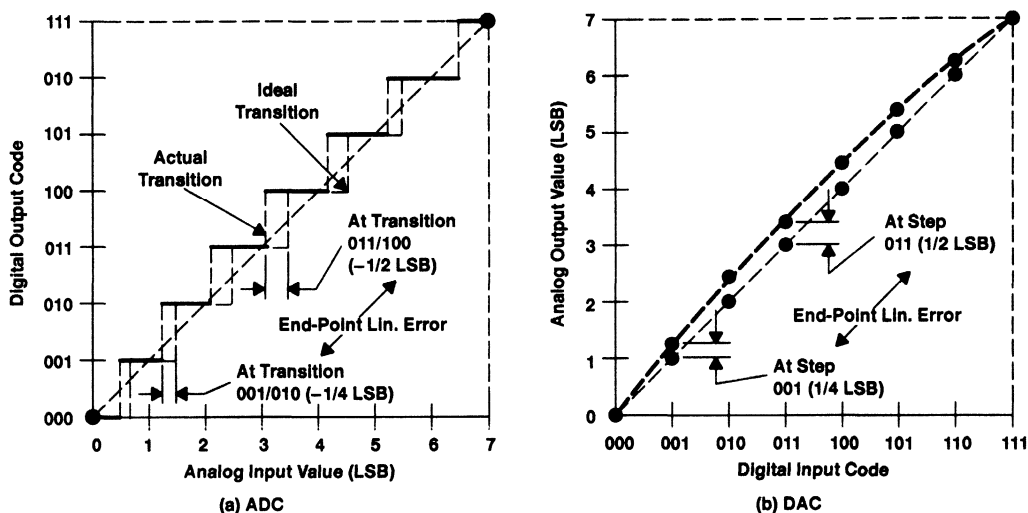
Differential Linearity Error of a Linear ADC or DAC

Figure 5. Differential Nonlinearity (DNL)

3.4 Integral Nonlinearity (INL) Error

The integral nonlinearity error shown in Figure 6 (sometimes seen as simply linearity error) is the deviation of the values on the actual transfer function from a straight line. This straight line can be either a best straight line which is drawn so as to minimize these deviations or it can be a line drawn between the end points of the transfer function once the gain and offset errors have been nullified. The second method is called end-point linearity and is the usual definition adopted since it can be verified more directly.

For an ADC the deviations are measured at the transitions from one step to the next, and for the DAC they are measured at each step. The name integral nonlinearity derives from the fact that the summation of the differential nonlinearities from the bottom up to a particular step, determines the value of the integral nonlinearity at that step.

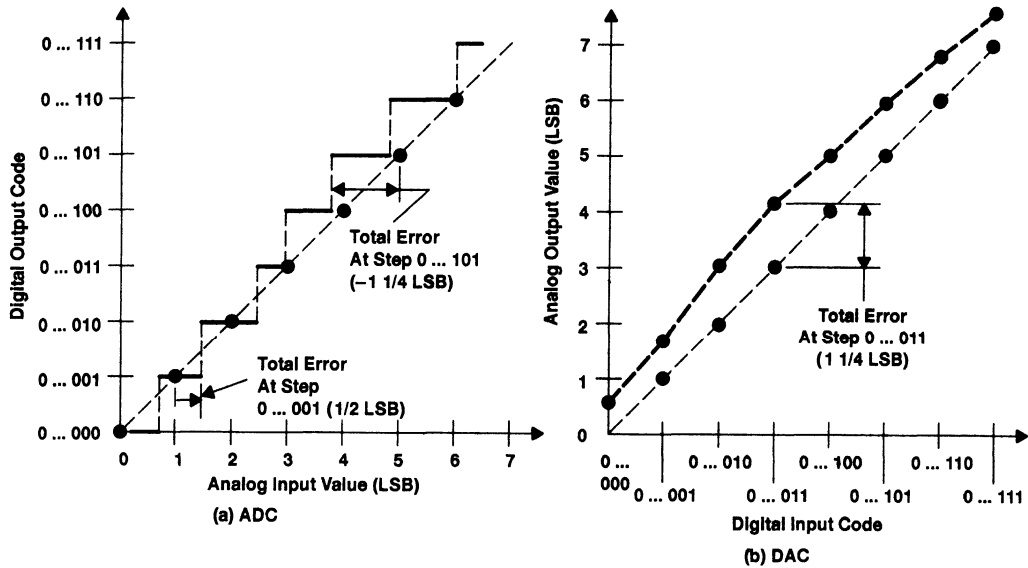


End-Point Linearity Error of a Linear 3-Bit Natural Binary-Coded ADC or DAC
(Offset Error and Gain Error are Adjusted to the Value Zero)

Figure 6. Integral Nonlinearity (INL) Error

3.5 Absolute Accuracy (Total) Error

The absolute accuracy or total error of an ADC as shown in Figure 7 is the maximum value of the difference between an analog value and the ideal midstep value. It includes offset, gain, and integral linearity errors and also the quantization error in the case of an ADC.



Absolute Accuracy or Total Error of a Linear ADC or DAC

Figure 7. Absolute Accuracy (Total) Error

4 APERTURE ERROR

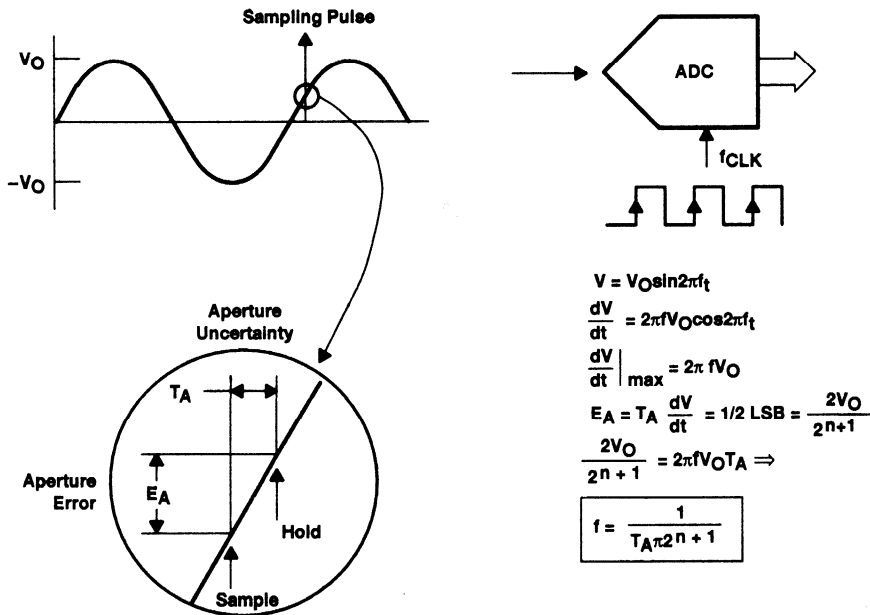


Figure 8. Aperture Error

Aperture error is caused by the uncertainty in the time at which the sample/hold goes from sample mode to hold mode as shown in Figure 8. This variation is caused by noise on the clock or the input signal. The effect of the aperture error is to set another limitation on the maximum frequency of the input sine wave because it defines the maximum slew rate of that signal. For a sine wave input as shown, the value of the input V is defined as:

$$V = V_O \sin 2\pi f t$$

The maximum slew rate occurs at the zero crossing point and is given by:

$$\left. \frac{dV}{dt} \right|_{\max} = 2\pi f V_O$$

If the aperture error is not to affect the accuracy of the converter, it must be less than 1/2 LSB at the point of maximum slew rate. For an n bit converter therefore:

$$E_A = T_A \frac{dV}{dt} = 1/2 \text{ LSB} = \frac{2 V_O}{2^{n+1}}$$

Substituting into this gives

$$\frac{2 V_O}{2^{n+1}} = 2\pi f V_O T_A$$

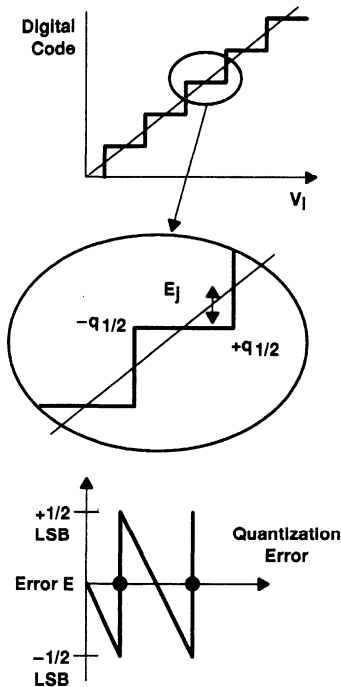
So that the maximum frequency is given by

$$f_{\text{MAX}} = \frac{1}{T_A \pi 2^{n+1}}$$

5 QUANTIZATION EFFECTS

The real world analog input to an ADC is a continuous signal with an infinite number of possible states, whereas the digital output is by its nature a discrete function with a number of different states determined by the resolution of the device. It follows from this therefore, that in converting from one form to the other, certain parts of the analog signal that were represented by a different voltage on the input are represented by the same digital code at the output. Some information has been lost and distortion has been introduced into the signal. This is quantization noise.

For the ideal staircase transfer function of an ADC, the error between the actual input and its digital form has a uniform probability density function if the input signal is assumed to be random. It can vary in the range $\pm 1/2$ LSB or $\pm q/2$ where q is the width of one step as shown in Figure 9.



Error at the j th step

$$E_j = (V_j - V_i)$$

The mean square error over the step

$$\bar{E}_j^2 = \frac{1}{q} \int_{-q/2}^{+q/2} E_j^2 dE = \frac{q^2}{12}$$

Assuming equal steps, the total error is

$$\bar{N}^2 = q^2/12 \text{ (Mean square quantization noise)}$$

For an input sine wave $F(t) = A \sin \omega t$, the signal power

$$\bar{F}^2(t) = \frac{1}{2\pi} \int_0^{2\pi} A^2 \sin^2 \omega t d\omega = \frac{A^2}{2}$$

$$\text{and } q = \frac{2A}{2^n} = \frac{A}{2^{n-1}}$$

$$\text{SNR} = 10 \text{ Log} \left(\frac{\bar{F}^2}{\bar{N}^2} \right) = 10 \text{ Log} \left(\frac{A^2/2}{A^2/3 \times 2^n} \right)$$

$$\text{SNR} = 6.02n + 1.76 \text{ dB}$$

Figure 9. Quantization Effects

Where

$$p(\epsilon) = \frac{1}{q} \text{ for } \left(-\frac{q}{2} \leq \epsilon \leq +\frac{q}{2} \right)$$

Otherwise

$$p(\epsilon) = 0$$

The average noise power (mean square) of the error over a step is given by

$$\bar{N}^2 = \frac{1}{q} \int_{-q/2}^{q/2} \epsilon^2 d\epsilon$$

which gives

$$\bar{N}^2 = \frac{q^2}{12}$$

The total mean square error, N^2 , over the whole conversion area is the sum of each quantization levels mean square multiplied by its associated probability. Assuming the converter is ideal, the width of each code step is identical and therefore has an equal probability. Hence for the ideal case

$$N^2 = \frac{q^2}{12}$$

Considering a sine wave input $F(t)$ of amplitude A so that

$$F(t) = A \sin \omega t$$

which has a mean square value of $F^2(t)$, where

$$F^2(t) = \frac{1}{2\pi} \int_0^{2\pi} A^2 \sin^2(\omega t) dt$$

which is the signal power. Therefore the signal to noise ratio SNR is given by

$$\text{SNR(dB)} = 10 \text{Log} \left[\left(\frac{A^2}{2} \right) / \left(\frac{q^2}{12} \right) \right]$$

But

$$q = 1 \text{ LSB} = \frac{2A}{2^n} = \frac{A}{2^{n-1}}$$

Substituting for q gives

$$\begin{aligned} \text{SNR(dB)} &= 10 \text{Log} \left[\left(\frac{A^2}{2} \right) / \left(\frac{A^2}{3 \times 2^{2n}} \right) \right] = 10 \text{Log} \left(\frac{3 \times 2^{2n}}{2} \right) \\ &\Rightarrow \underline{\underline{6.02n + 1.76 \text{dB}}} \end{aligned}$$

This gives the ideal value for an n bit converter and shows that each extra 1 bit of resolution provides approximately 6 dB improvement in the SNR.

In practice, the errors mentioned in section 3 introduce nonlinearities that lead to a reduction of this value. The limit of a 1/2 LSB differential linearity error is a missing code condition which is equivalent to a reduction of 1 bit of resolution and hence a reduction of 6 dB in the SNR. This then gives a worst case value of SNR for an n -bit converter with 1/2 LSB linearity error.

$$\text{SNR (worst case)} = 6.02n + 1.76 - 6 = 6.02n - 4.24 \text{ dB}$$

Hence we have established the boundary conditions for the choice of the resolution of the converter based upon a desired level of SNR.

6 IDEAL SAMPLING

In converting a continuous time signal into a discrete digital representation, the process of sampling is a fundamental requirement. In an ideal case, sampling takes the form of a pulse train of impulses which are infinitesimally narrow yet have unit area. The reciprocal of the time between each impulse is called the sampling rate. The input signal is also idealized by being truly bandlimited, containing no components in its spectrum above a certain value (see Figure 10).

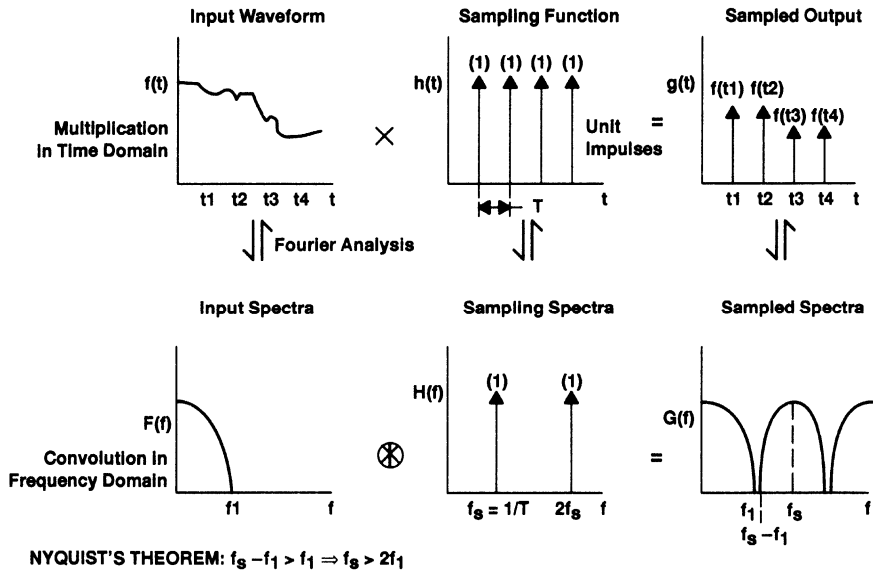


Figure 10. Ideal Sampling

The ideal sampling condition shown is represented in both the frequency and time domains. The effect of sampling in the time domain is to produce an amplitude modulated train of impulses representing the value of the input signal at the instant of sampling. In the frequency domain, the spectrum of the pulse train is a series of discrete frequencies at multiples of the sampling rate. Sampling convolves the spectra of the input signal with that of the pulse train to produce the combined spectrum shown, with double sidebands around each discrete frequency which are produced by the amplitude modulation. In effect some of the higher frequencies are folded back so that they produce interference at lower frequencies. This interference causes distortion which is called aliasing.

If the input signal is bandlimited to a frequency f_1 and is sampled at frequency f_s , as shown in the figure, overlap (and hence aliasing) does not occur if

$$f_1 < f_s - f_1 \quad \text{i.e., } 2f_1 < f_s$$

Therefore if sampling is performed at a frequency at least twice as great as the maximum frequency of the input signal, no aliasing occurs and all of the signal information can be extracted. This is Nyquist's Sampling Theorem, and it provides the basic criteria for the selection of the sampling rate required by the converter to process an input signal of a given bandwidth.

7 REAL SAMPLING

The concept of an impulse is a useful one to simplify the analysis of sampling. However, it is a theoretical ideal which can be approached but never reached in practice. Instead the real signal is a series of pulses with the period equalling the reciprocal of the sampling frequency. The result of sampling with this pulse train is a series of amplitude modulated pulses (see Figure 11).

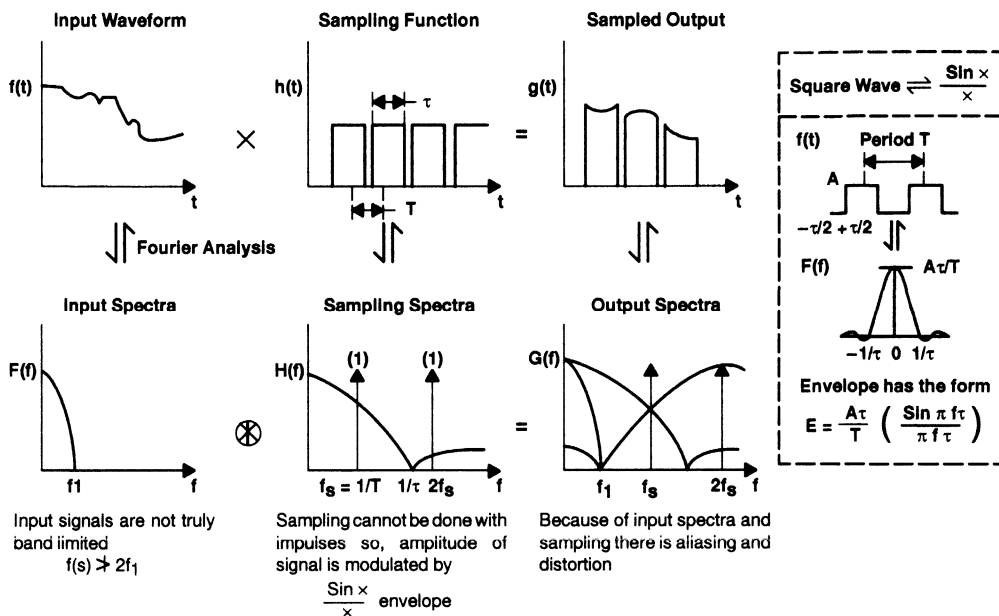


Figure 11. Real Sampling

Examining the spectrum of the square wave pulse train shows a series of discrete frequencies, as with the impulse train, but the amplitude of these frequencies is modified by an envelope which is defined by $(\sin x)/x$ [sometimes written $\text{sinc}(x)$] where x in this case is $\pi f_s \tau$. For a square wave of amplitude A , the envelope of the spectrum is defined as

$$\text{Envelope} = A \left(\frac{\tau}{T} \right) \left[\frac{\sin(\pi f_s \tau)}{\pi f_s \tau} \right]$$

The error resulting from this can be controlled with a filter which compensates for the sinc envelope. This can be implemented as a digital filter, in a DSP, or using conventional analog techniques.

8 ALIASING EFFECTS AND CONSIDERATIONS

No signal is truly deterministic and therefore in practice has infinite bandwidth. However, the energy of higher frequency components becomes increasingly smaller so that at a certain value it can be considered to be irrelevant. This value is a choice that must be made by the system designer.

As shown, the amount of aliasing is affected by the sampling frequency and by the relevant bandwidth of the input signal, filtered as required. The factor that determines how much aliasing can be tolerated is ultimately the resolution of the system. If the system has low resolution, then the noise floor is already relatively high and aliasing does not have a significant effect. However, with a high resolution system, aliasing can increase the noise floor considerably and therefore needs to be controlled more completely.

One way to prevent aliasing is to increase the sampling rate, as shown. However, the frequency is limited by the type of converter used and also by the maximum clock rate of the digital processor receiving and transmitting the data. Therefore, to reduce the effects of aliasing to within acceptable levels, analog filters must be used to alter the input signal spectrum (see Figure 12).

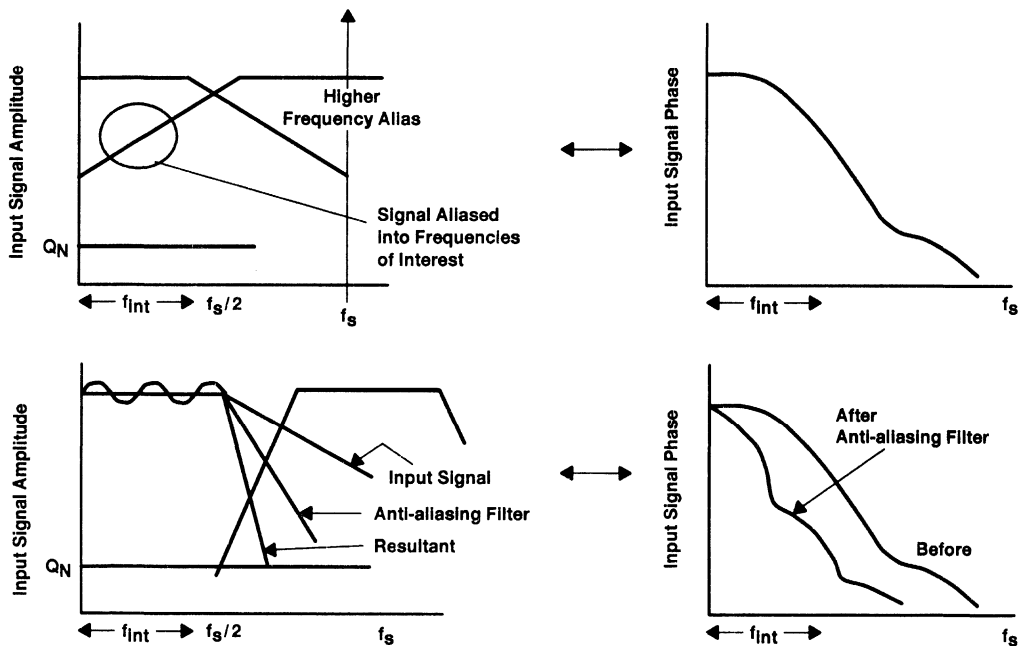


Figure 12. Aliasing Effects and Considerations

8.1 Choice of Filter

As shown with sampling, there is an ideal solution to the choice of a filter and a practical realization that compromises must be made. The ideal filter is a so-called brickwall filter which introduces no attenuation in the passband, and then cuts down instantly to infinite attenuation in the stopband. In practice, this is approximated by a filter that introduces some attenuation in the passband, has a finite rolloff, and passes some frequencies in the stopband. It can also introduce phase distortion as well as amplitude distortion. The choice of the filter order and type must be decided upon so as to best meet the requirements of the system.

8.2 Types of Filter

The basic types of filters available to the designer are briefly presented for comparison purposes. This is not intended to be a full analysis of the subject; therefore, other texts should be referenced for more details.

8.2.1 Butterworth Filter

A Butterworth (maximally flat) filter is the most commonly used general purpose filter. It has a monotonic passband with the attenuation increasing up to its 3-dB point which is known as the natural frequency. This frequency is the same regardless of the order of the filter. However, by increasing the order of the filter, the roll-off in the passband moves closer to its natural frequency and the roll-off in the transition region between the natural frequency and the stopband becomes sharper.

8.2.2 Chebyshev Filter

The Chebyshev equal ripple filter distributes the roll-off across the whole passband. It introduces more ripple in the passband but provides a sharper roll-off in the transition region. This type of filter has poorer transient and step responses due to its higher Q values in the stages of the filter.

8.2.3 Inverse Chebyshev Filter

Both the Butterworth and Chebyshev filters are monotonic in the transition region and stopband. Since ripple is allowed in the stopband, it is possible to make the roll-off sharper. This is the principle of the Inverse Chebyshev, based on the reciprocal of the angular frequency in the Chebyshev filter response. This filter is monotonic in the passband and can be flatter than the Butterworth filter while providing a greater initial roll-off than the Chebyshev filter.

8.2.4 Cauer Filter

The Cauer or (Elliptic) filter is nonmonotonic in both the pass and stop bands, but provides the greatest roll-off in any of the standard filter configurations.

8.2.5 Bessel-Thomson Filter

All of the types mentioned above introduce nonlinearities into the phase relationship of the component frequencies of the input spectrum. This can be a problem in some applications when the signal is reconstructed. The Bessel-Thomson or linear delay filter is designed to introduce no phase distortion but this is achieved at the expense of a poorer amplitude response.

In general, the performance of all of these types can be improved by increasing the number of stages, i.e., the order of the filter. The penalty for this of course is the increased cost of components and board space required. For this reason, an integrated solution using switched capacitor filter building blocks which provide comparable performance with a discrete solution over a range of frequencies from about 1 kHz to 100 kHz might be appropriate. They also provide the designer with a compact and cost effective solution.

8.3 TLC04 Anti-Aliasing Butterworth Filter

The TLC04 fourth order Butterworth filter features include the following:

- Low clock to cutoff frequency error . . . 0.8%
- Cutoff depends only on stability of external clock
- Cutoff range of 0.1 Hz to 30 kHz
- 5-V to 12-V operation
- Self clocking or both TTL and COS compatible

As detailed previously the Butterworth filter generally provides the best compromise in filter configurations and is by far the easiest to design. The Butterworth filter's characteristic is based on a circle which means that when designing filters, all stages to the filter have the same natural frequency enabling simpler filter design. Most modern designs which use operational amplifiers are based on building the whole transfer function by a series of second order numerator and denominator stages (a Biquad stage). The Butterworth design is simplified, when using these stages, because each stage has the same natural frequency. This can easily be converted to a switched capacitor filter (SCF) which has very good capacitor matching and accurately synthesized RC time constants.

The switched capacitor technique is demonstrated in Figure 13. Two clocks operating at the same frequency but in complete antiphase, alternately connect the capacitor C_2 to the input and the inverting input of an operational amplifier. During Φ_1 , charge Q flows onto the capacitor equal to $V_1 C_2$. The switch is considered to be ideal so that there is no series resistance and the capacitor charges instantaneously. During Φ_2 , the switches change so that C_2 is now connected to the virtual earth at the operational amplifier input. It discharges instantaneously delivering the stored charge Q .

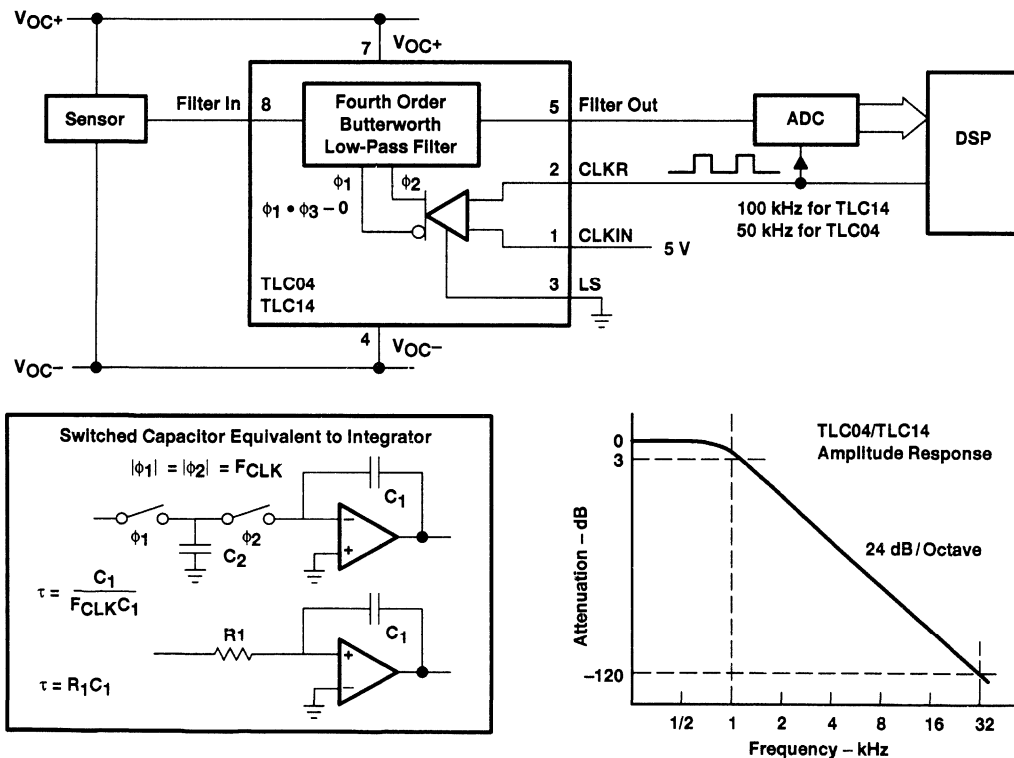


Figure 13. TLC04 Anti-aliasing Butterworth Filter

The average current that flows I_{AV} depends on the frequency of the clocks T so that

$$I_{AV} = \frac{Q}{T} = V_I \frac{C_2}{T} = V_I C_2 F_{CLK}$$

Therefore, the switched capacitor looks like a resistor of value

$$R_{eq} = \frac{V_I}{I_{AV}} = \frac{1}{C_2 F_{CLK}}$$

The advantage of the technique is that the time constant of the integrator can be programmed by altering this equivalent resistance, and this is done by simply altering the clock frequency. This provides precision in the filter design, because the time constant then depends on the ratio of two capacitors which can be fabricated in silicon to track each other very closely with voltage and temperature. Note that the analysis assumes V_I to be constant so that for an ac signal, the clock frequency must be much higher than the frequency of the input.

The TLC04 is one such filter which is internally configured to provide the Butterworth low-pass filter response, and the cut-off frequency for the device is controlled by a digital clock. For this device, the cut-off frequency is set simply by the clock frequency so that the clock to cut-off frequency ratio is 50:1 with an accuracy of 0.8%. This enables the cut-off frequency of the filter to be tied to the sampling rate, so that only one fundamental clock signal is required for the system as a whole. Another advantage of SCF techniques means that fourth order filters can be attained using only one integrated circuit and they are much more easily controlled.

The response of an n th order Butterworth filter is described by the following equation.

$$\text{Attenuation} = \left[1 + \left(\frac{f}{f_c} \right)^{2n} \right]^{1/2}$$

The table below lists the fourth order realization in the TLC04.

FREQUENCY	ATTENUATION (FACTOR)	ATTENUATION (dB)	PHASE (DEGREE)
$F_c/2$	0.998	0.02	28.6
F_c	0.707	3	45
$2F_c$	0.0624	24	63.4
$4F_c$	0.00391	48	76
$8F_c$	0.000244	72	82.9
$12F_c$	0.000048	86	85.2
$16F_c$	0.000015	96	86.4

This means that sampling at 8 times the cut off frequency gives an input-to-aliased signal ratio of 72 dB, which is less than ten bit quantization noise distortion.

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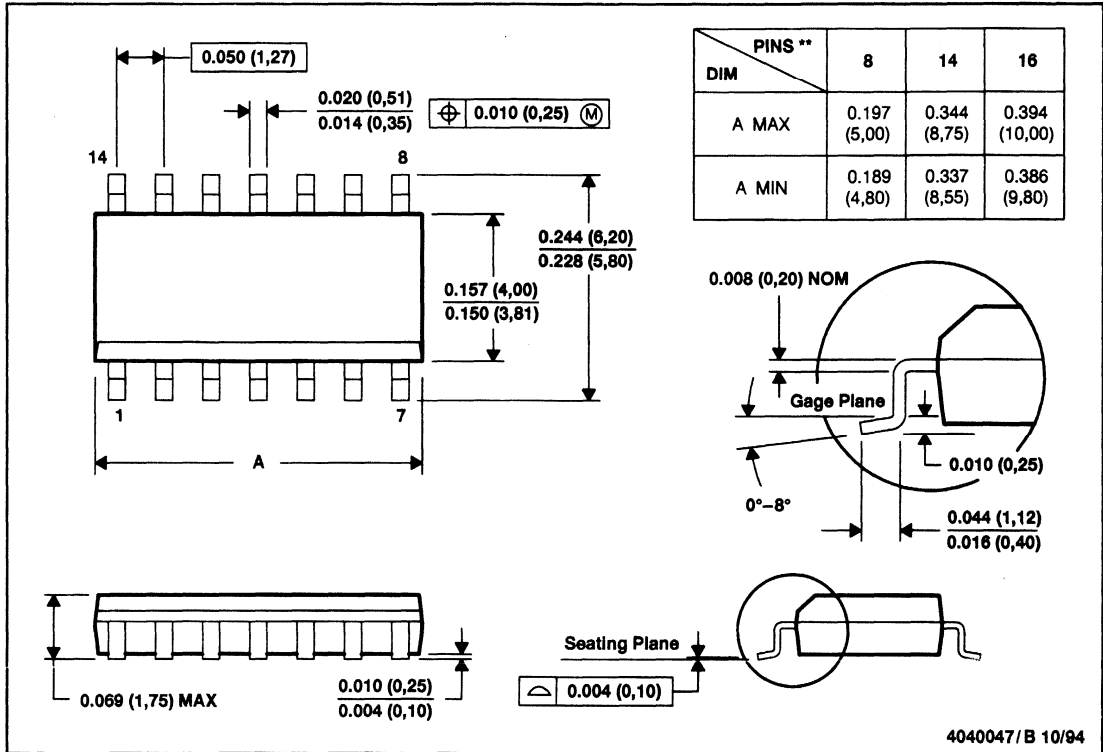


Mechanical Data

D (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Four center pins are connected to die mount pad
 E. Falls within JEDEC MS-012

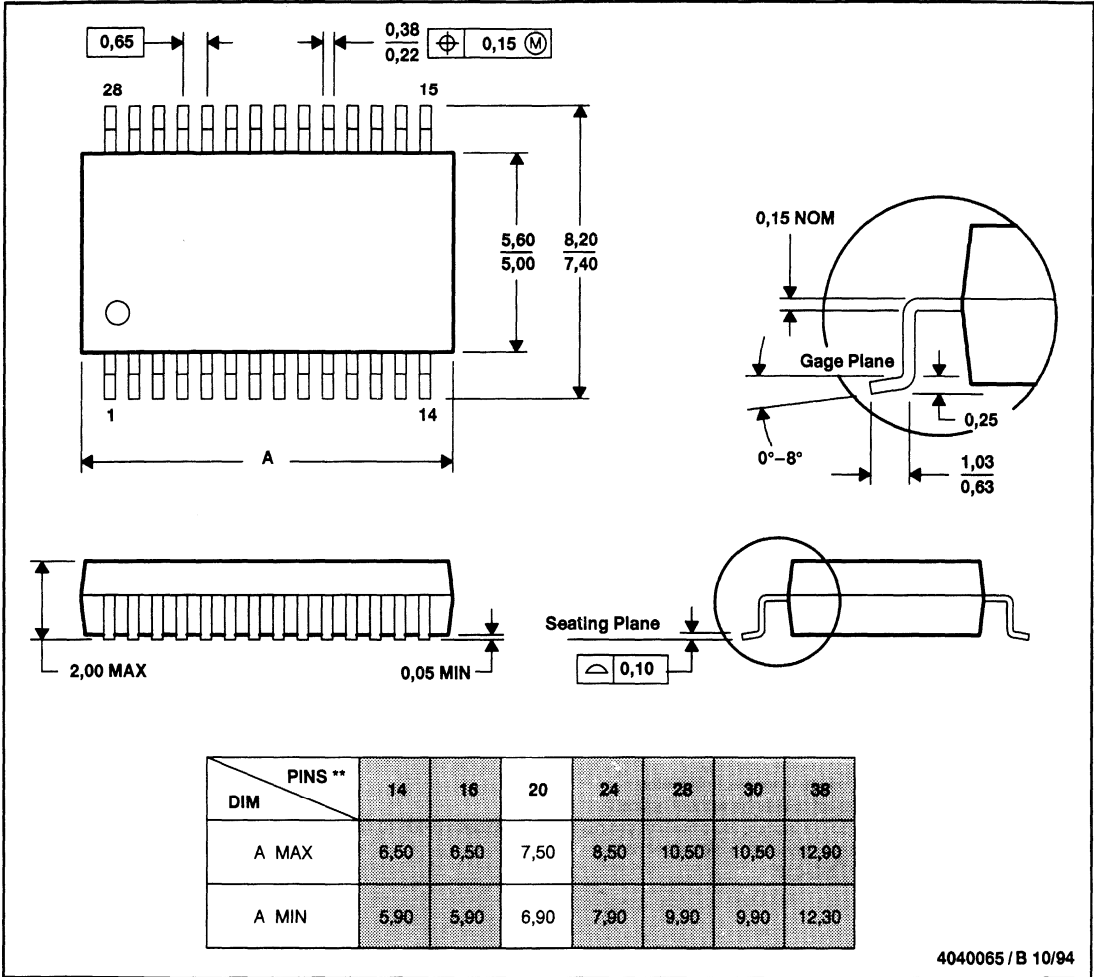
MECHANICAL DATA

AUGUST 1995

DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

28 PIN SHOWN



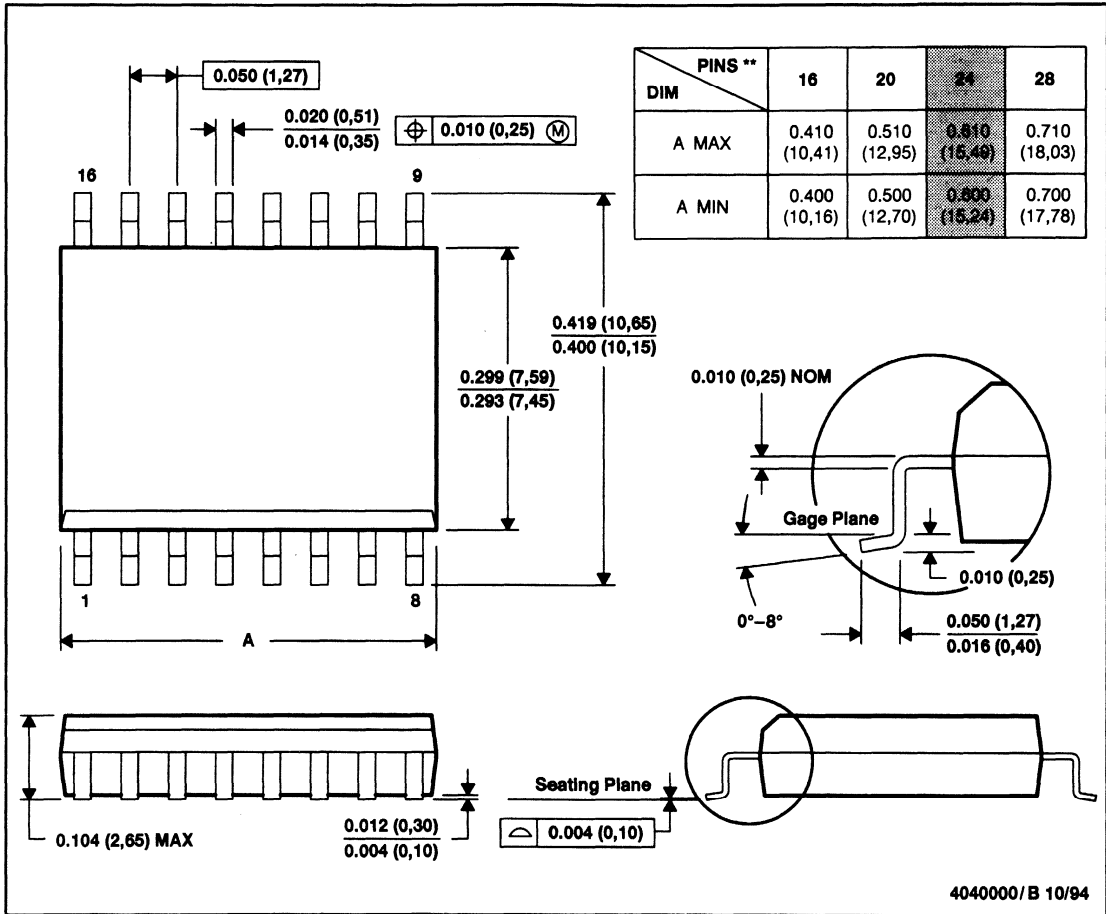
- NOTES:
- All linear dimensions are in millimeters.
 - This drawing is subject to change without notice.
 - Body dimensions do not include mold flash or protrusion not to exceed 0,15.
 - Falls within JEDEC MO-150

AUGUST 1995

DW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

16 PIN SHOWN



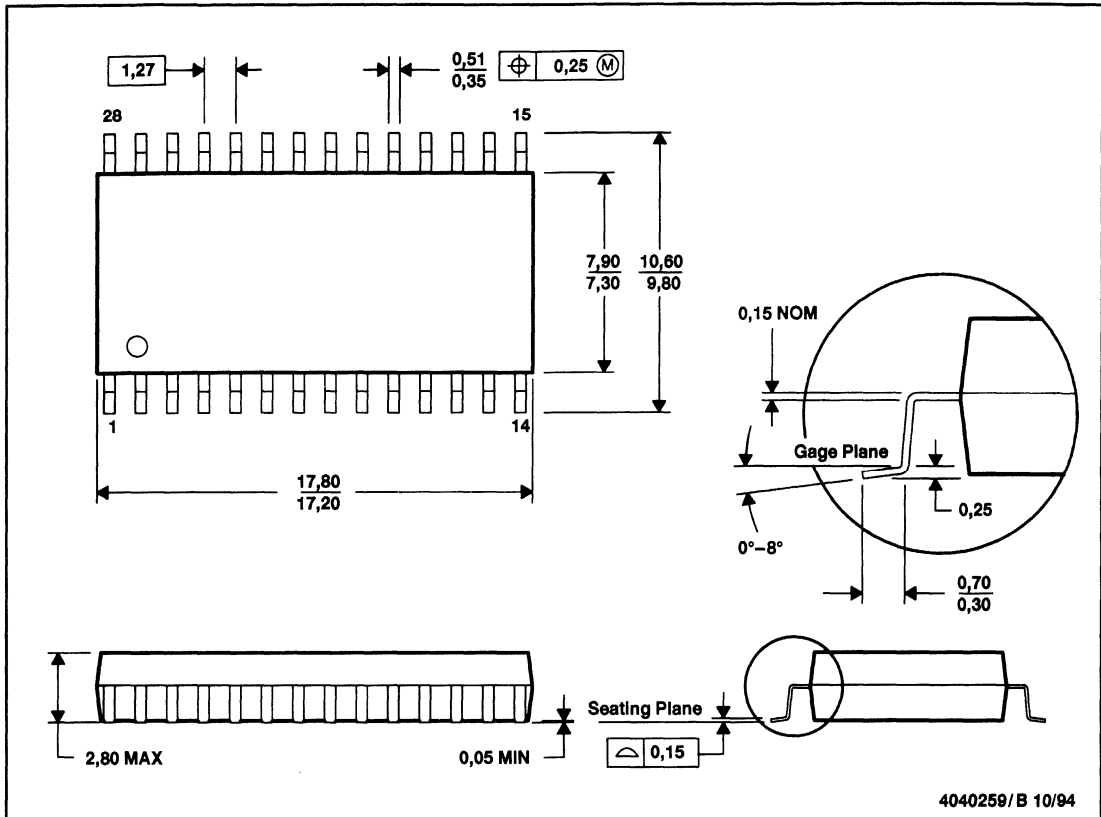
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 D. Falls within JEDEC MS-013

MECHANICAL DATA

AUGUST 1995

DWB (R-PDSO-G28)

PLASTIC SMALL-OUTLINE PACKAGE



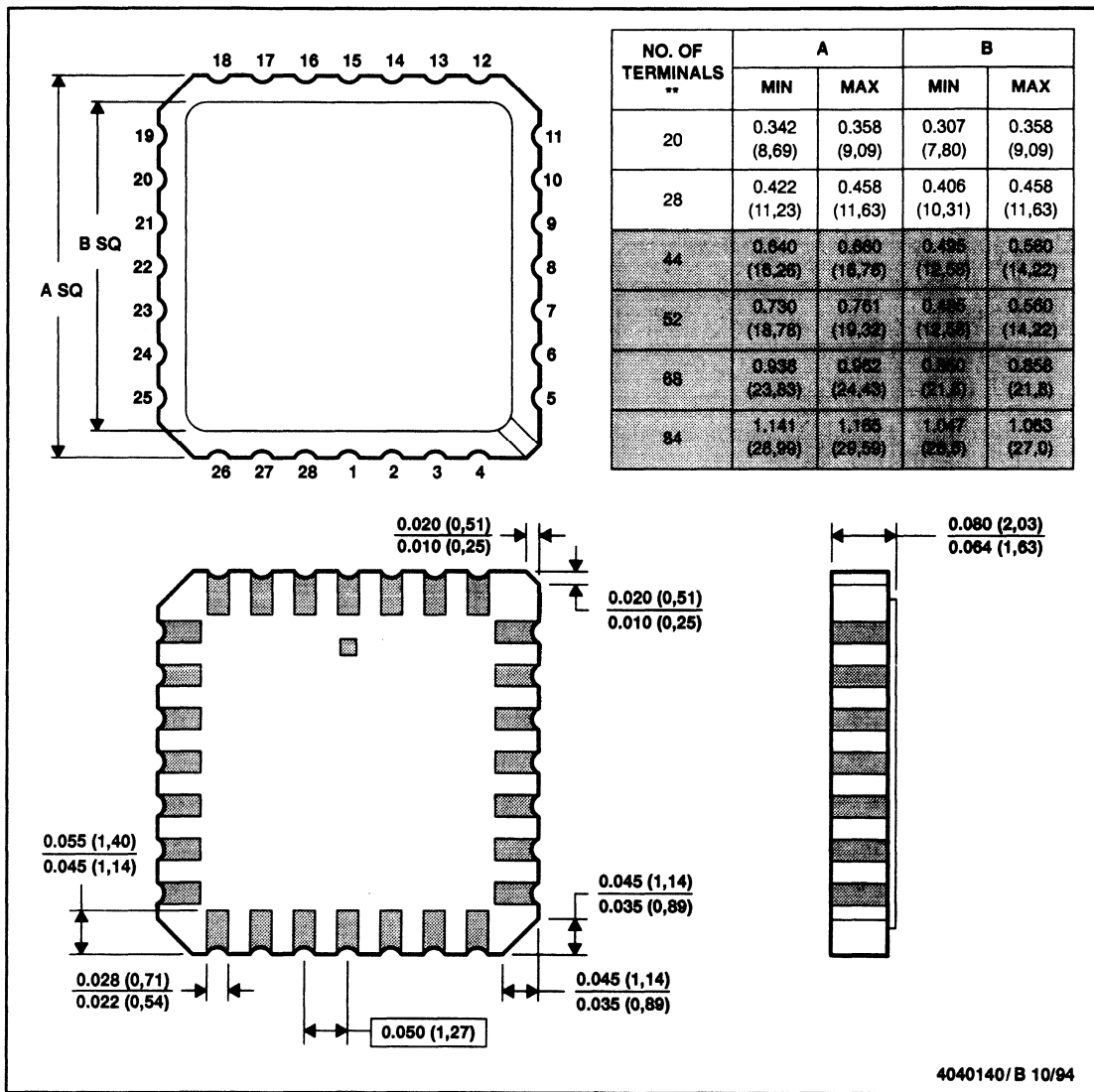
- NOTES: A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions include mold flash or protrusion.

AUGUST 1995

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a metal lid.
 D. The terminals are gold plated.
 E. Falls within JEDEC MS-004

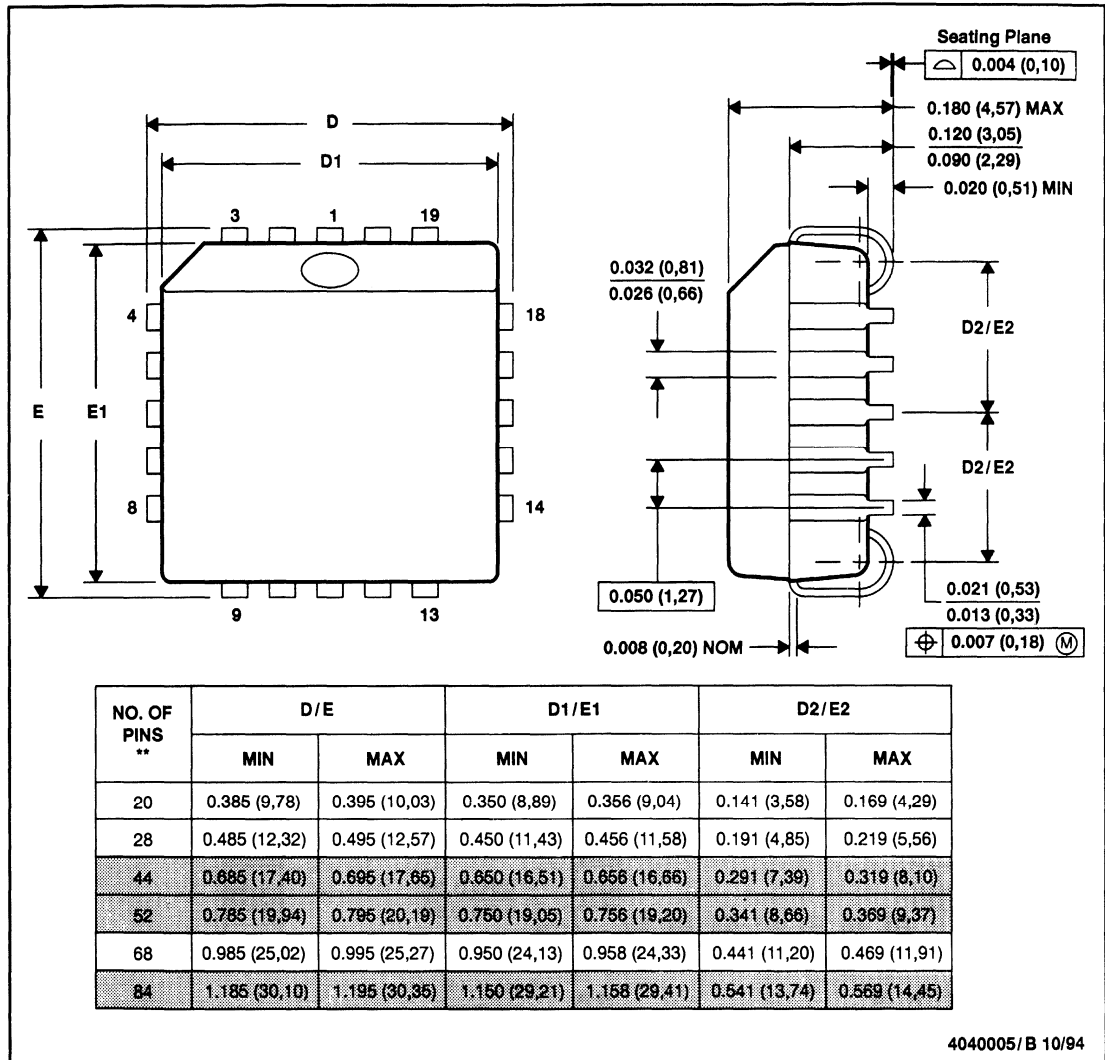
MECHANICAL DATA

AUGUST 1995

FN (S-PQCC-J**)

PLASTIC J-LEADED CHIP CARRIER

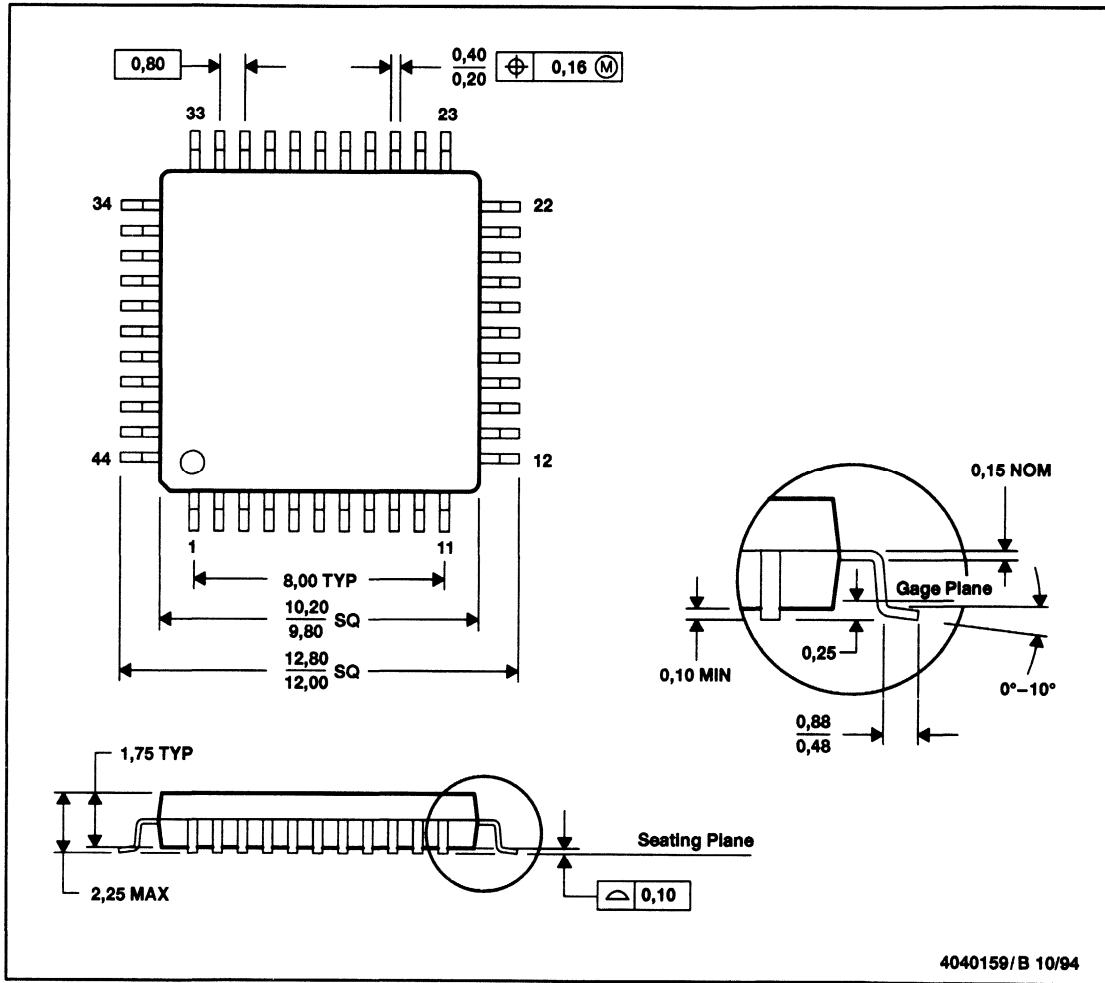
20 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-018

FR (S-PDFP-G44)

PLASTIC QUAD FLATPACK



NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.

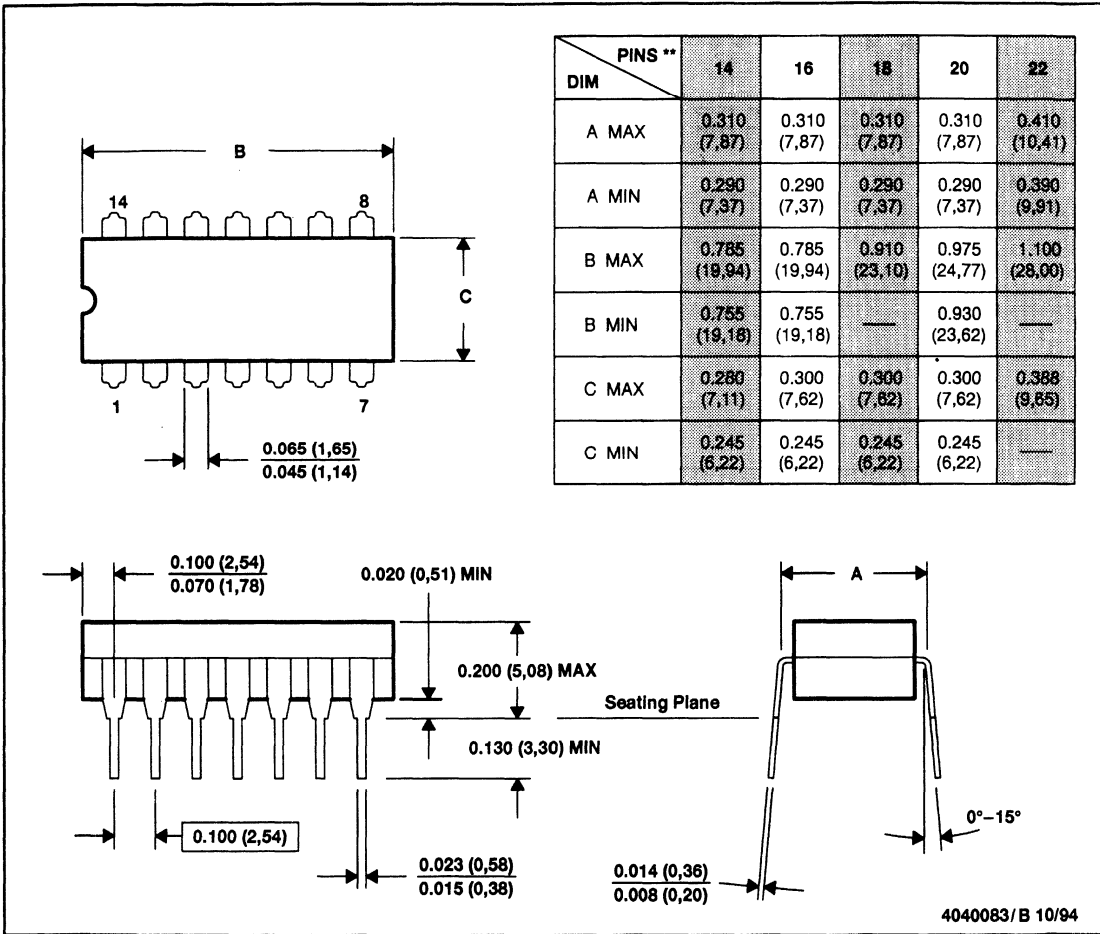
MECHANICAL DATA

AUGUST 1995

J (R-GDIP-T**)

CERAMIC DUAL-IN-LINE PACKAGE

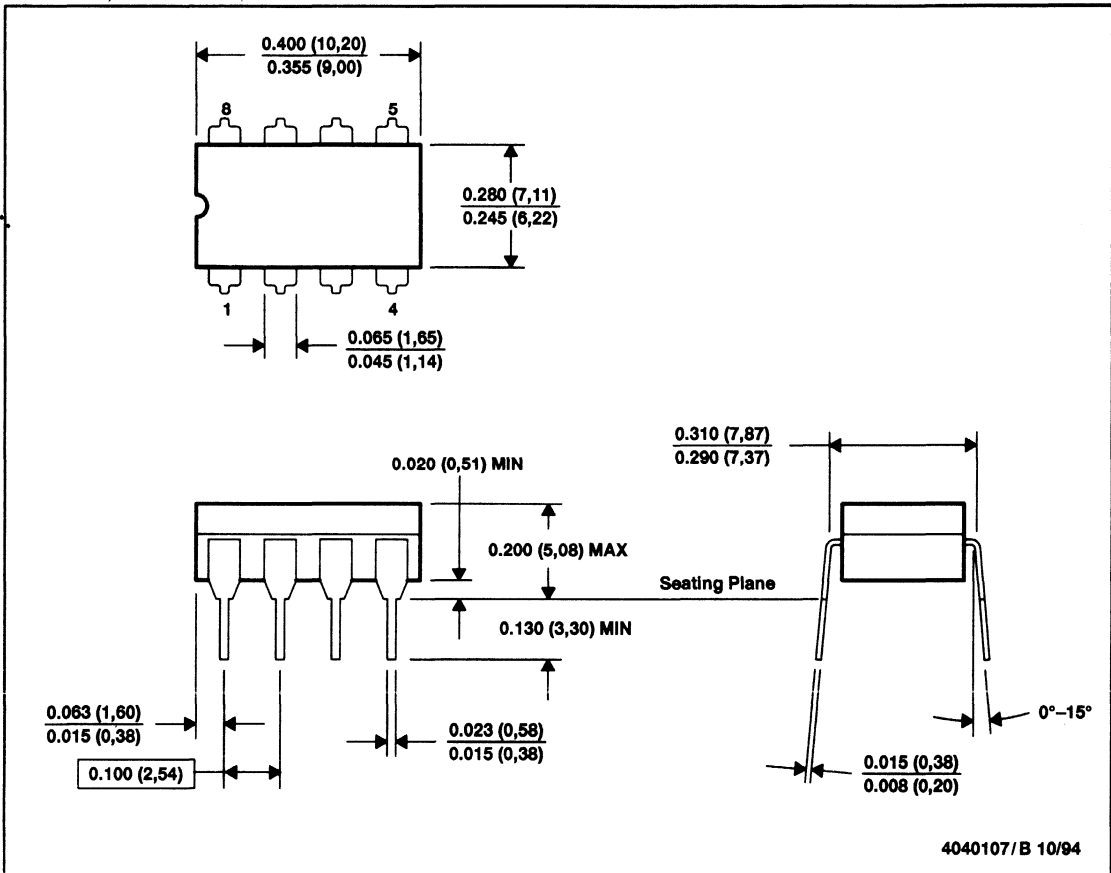
14 PIN SHOWN



- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. This package can be hermetically sealed with a ceramic lid using glass frit.
 D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 E. Falls within MIL-STD-1835 GDIP1-T14, GDIP1-T16, GDIP1-T18, GDIP1-T20, and GDIP1-T22

JG (R-GDIP-T8)

CERAMIC DUAL-IN-LINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a ceramic lid using glass frit.
 - D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only
 - E. Falls within MIL-STD-1835 GDIP1-T8

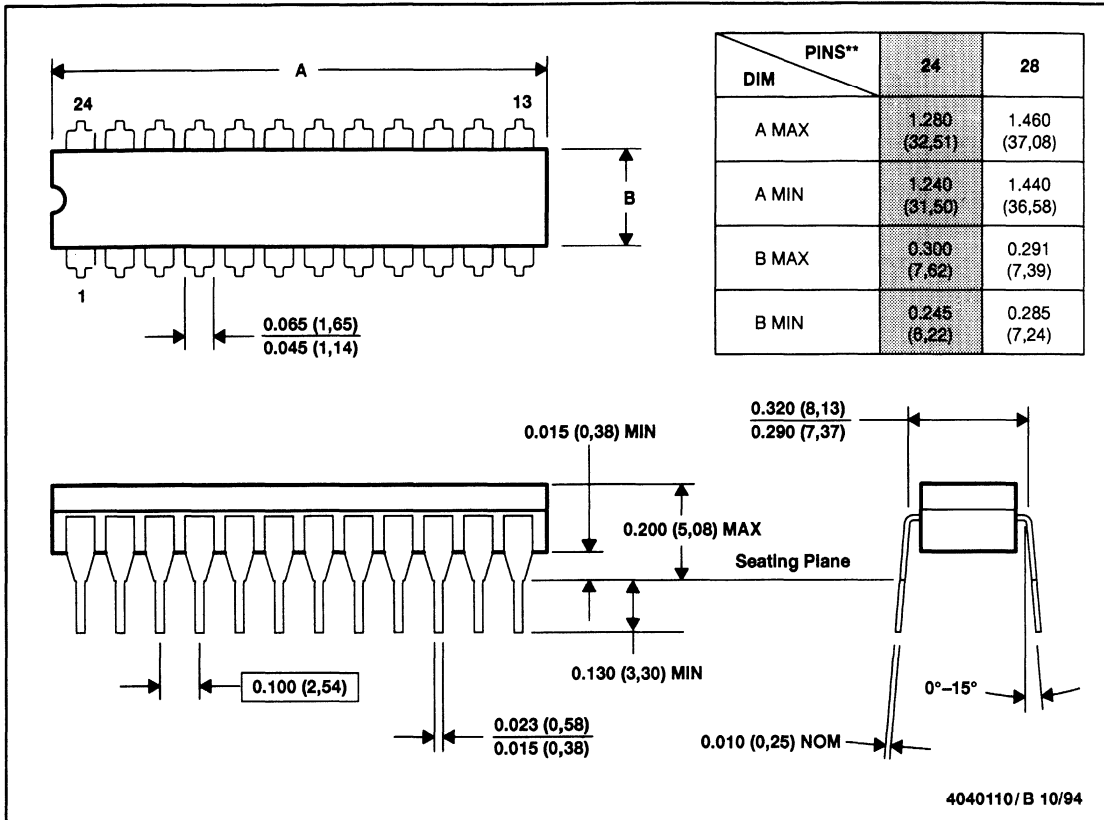
MECHANICAL DATA

AUGUST 1995

JT (R-GDIP-T**)

CERAMIC DUAL-IN-LINE PACKAGE

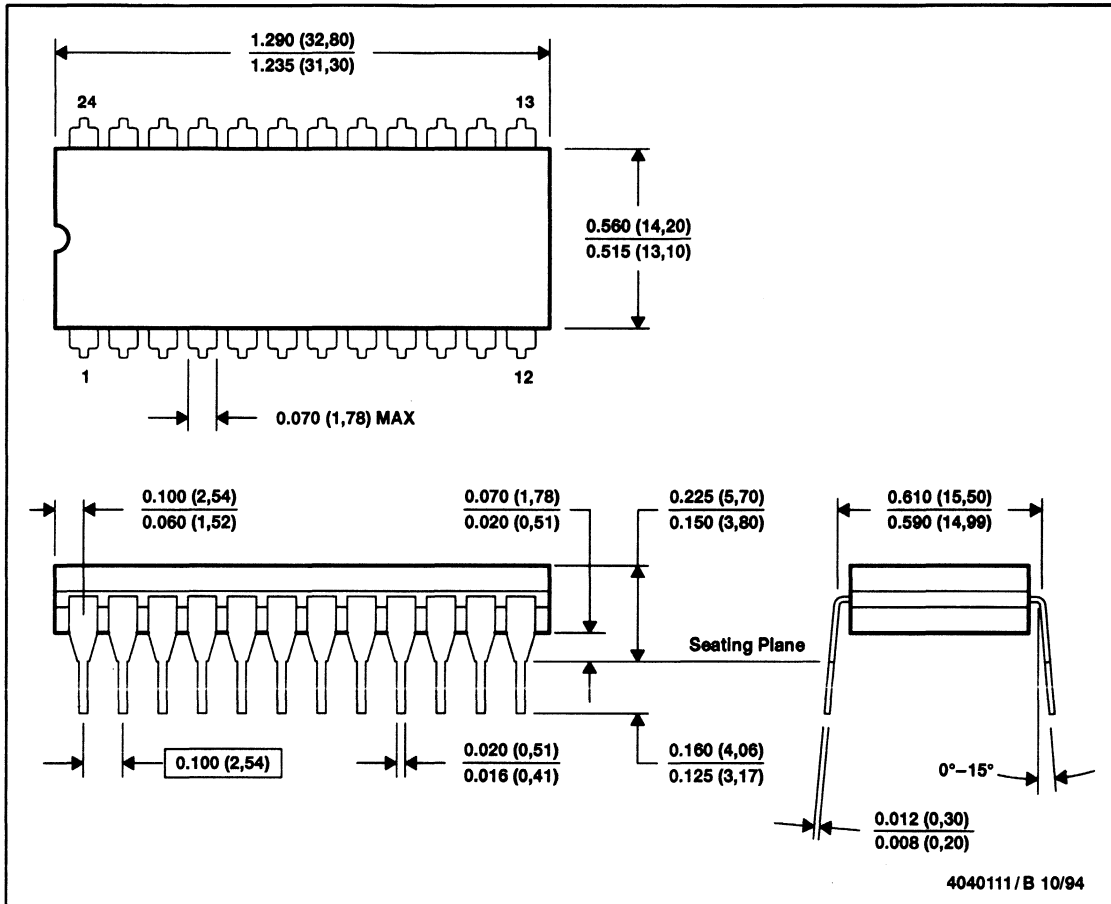
24 PIN SHOWN



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only
 - Falls within MIL-STD-1835 GDIP-T24 and GDIP-T28 and JEDEC MO-058AA and MO-058AB

JW (R-GDIP-T24)

CERAMIC DUAL-IN-LINE PACKAGE



- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package can be hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only
 - Falls within MIL-STD-1835 GDIP5-T24

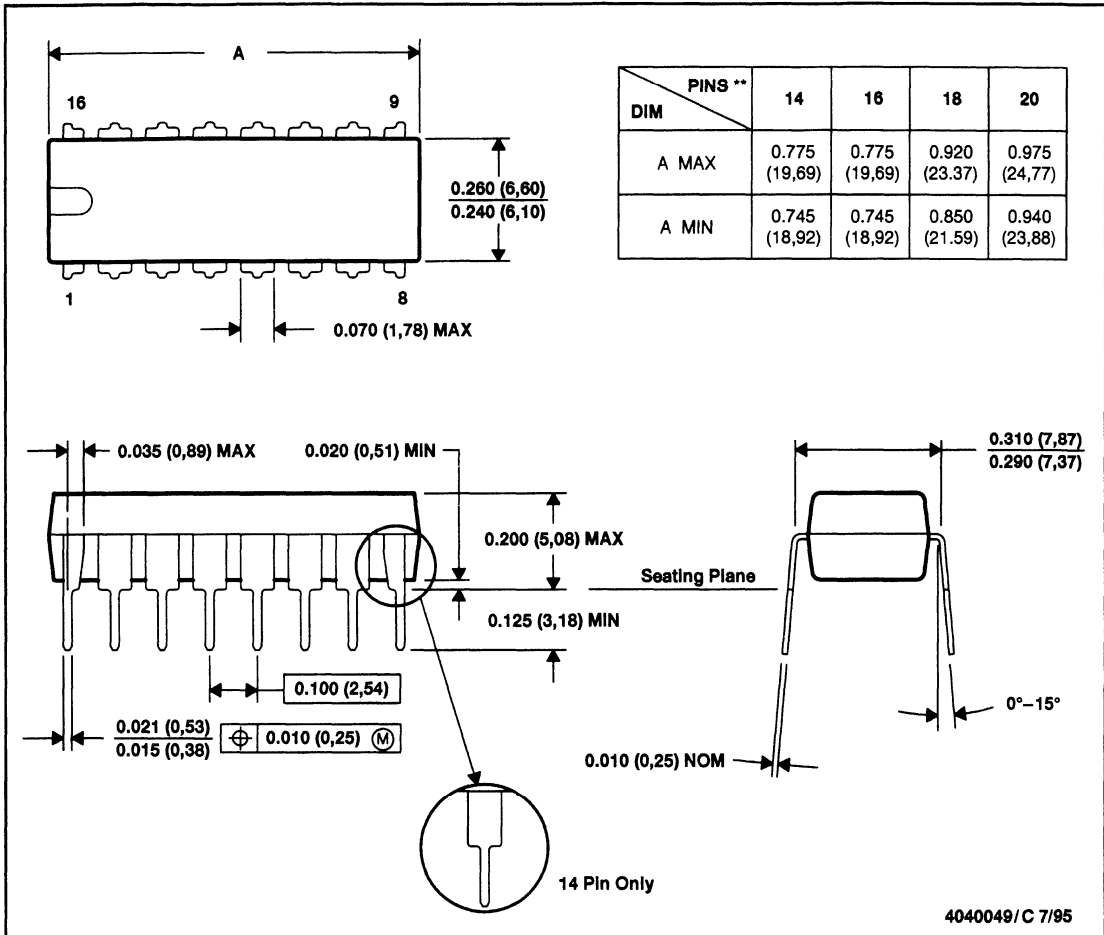
MECHANICAL DATA

AUGUST 1995

N (R-PDIP-T)**

PLASTIC DUAL-IN-LINE PACKAGE

16 PIN SHOWN



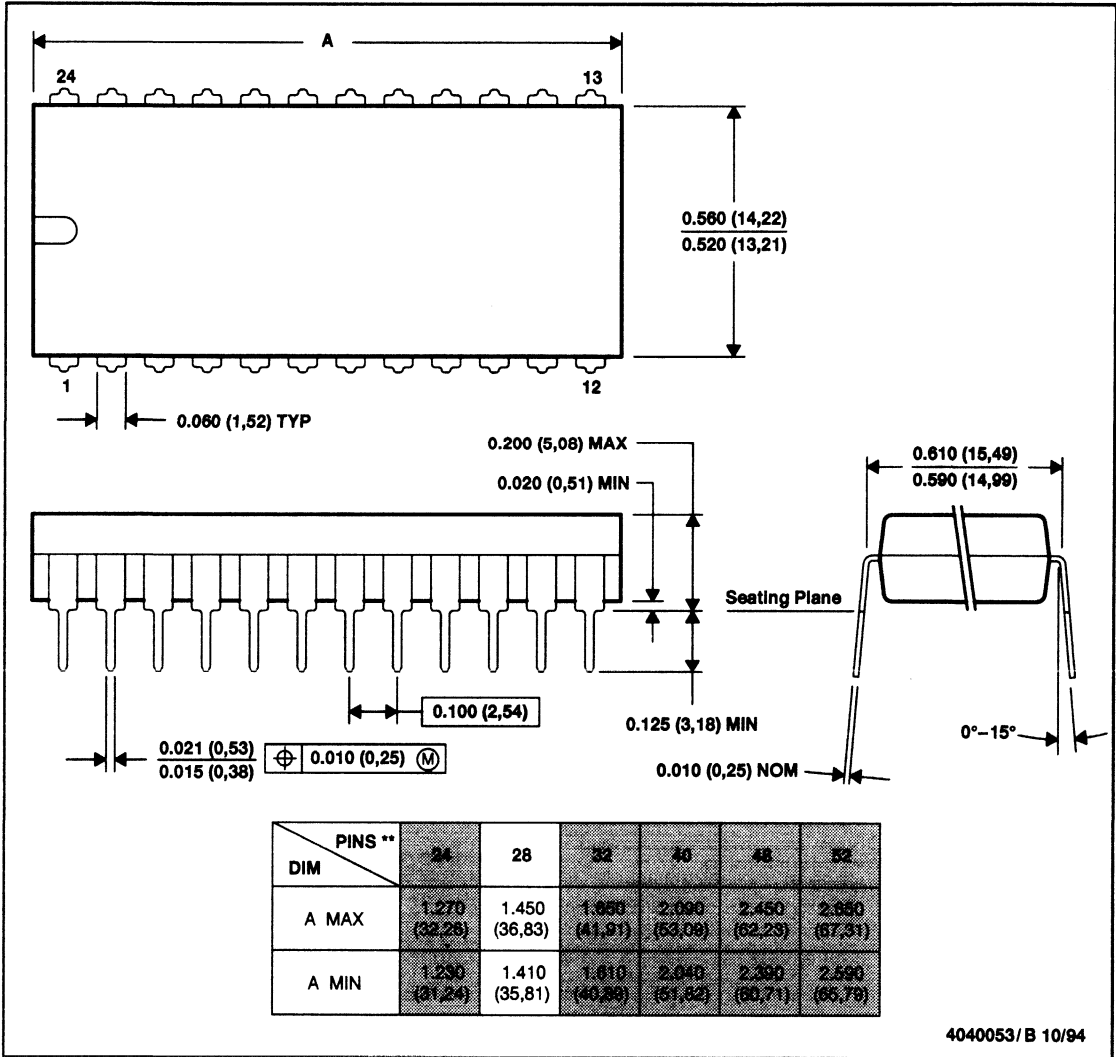
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-001 (20-pin package is shorter than MS-001)

AUGUST 1985

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



4040053/B 10/84

- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-011
 D. Falls within JEDEC MS-015 (32 pin only)

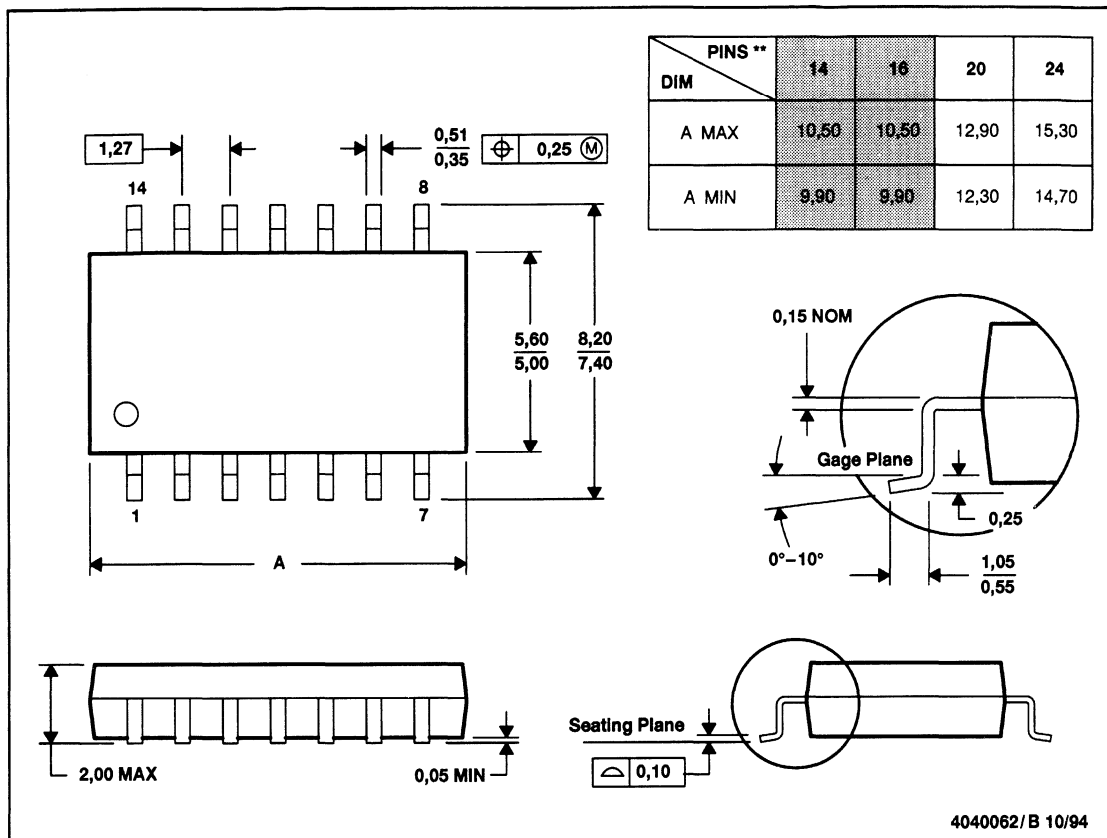
MECHANICAL DATA

AUGUST 1995

NS (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN

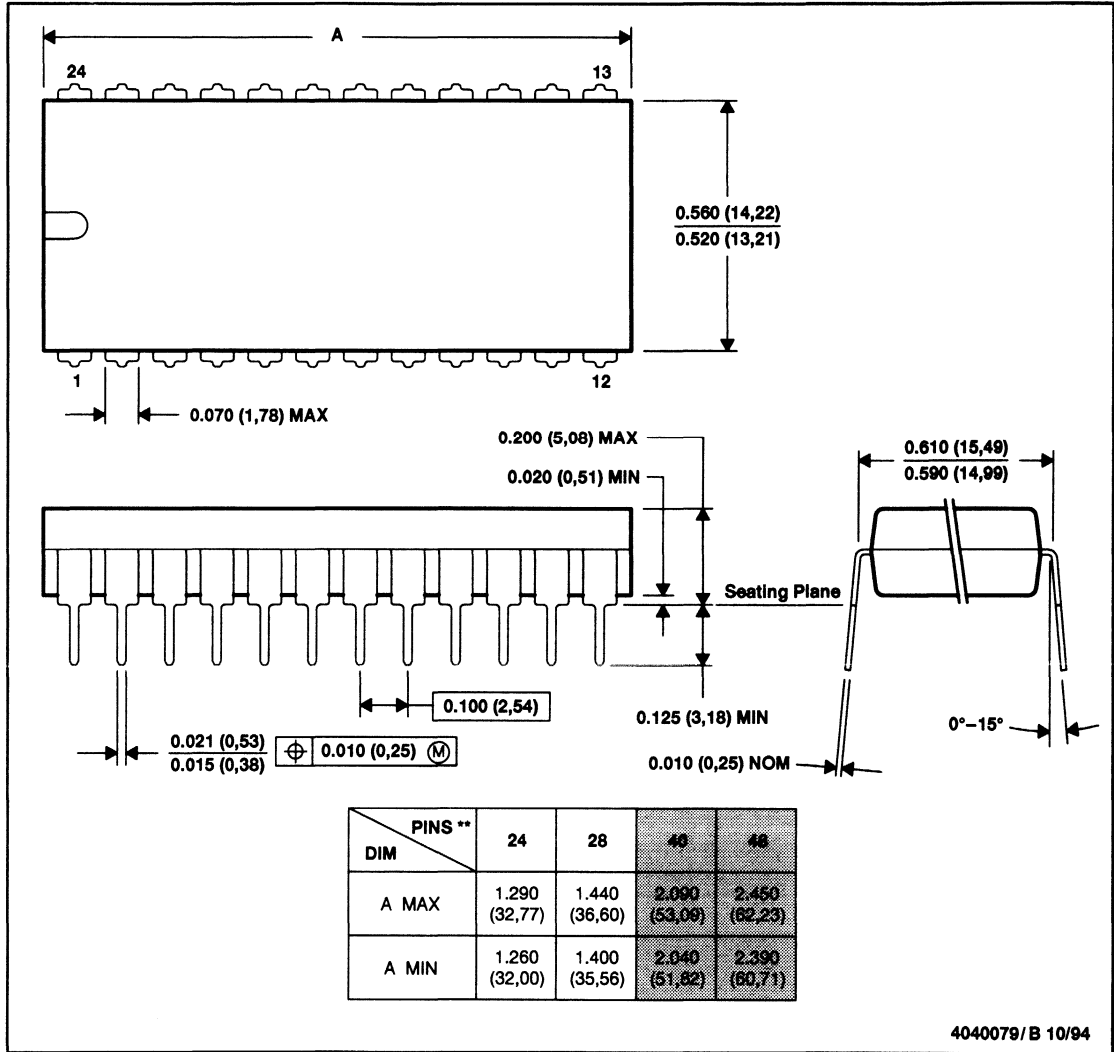


- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

NW (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

24 PIN SHOWN



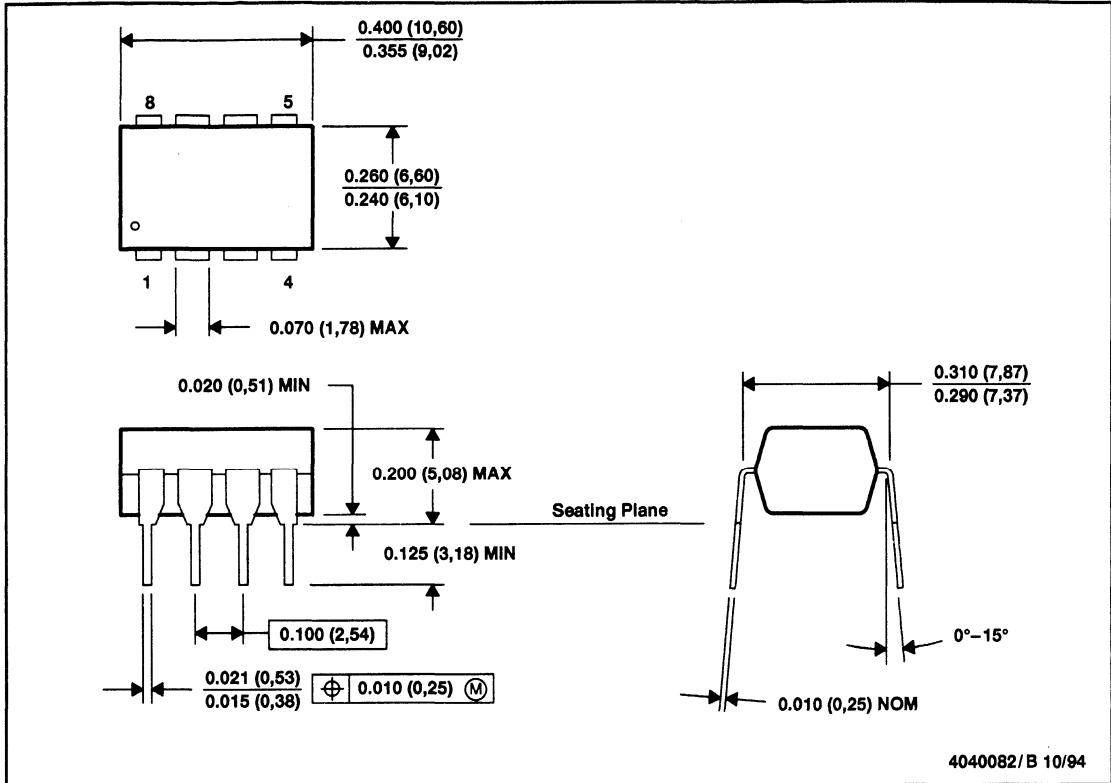
- NOTES: A. All linear dimensions are in inches (millimeters).
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MS-011

MECHANICAL DATA

AUGUST 1995

P (R-PDIP-T8)

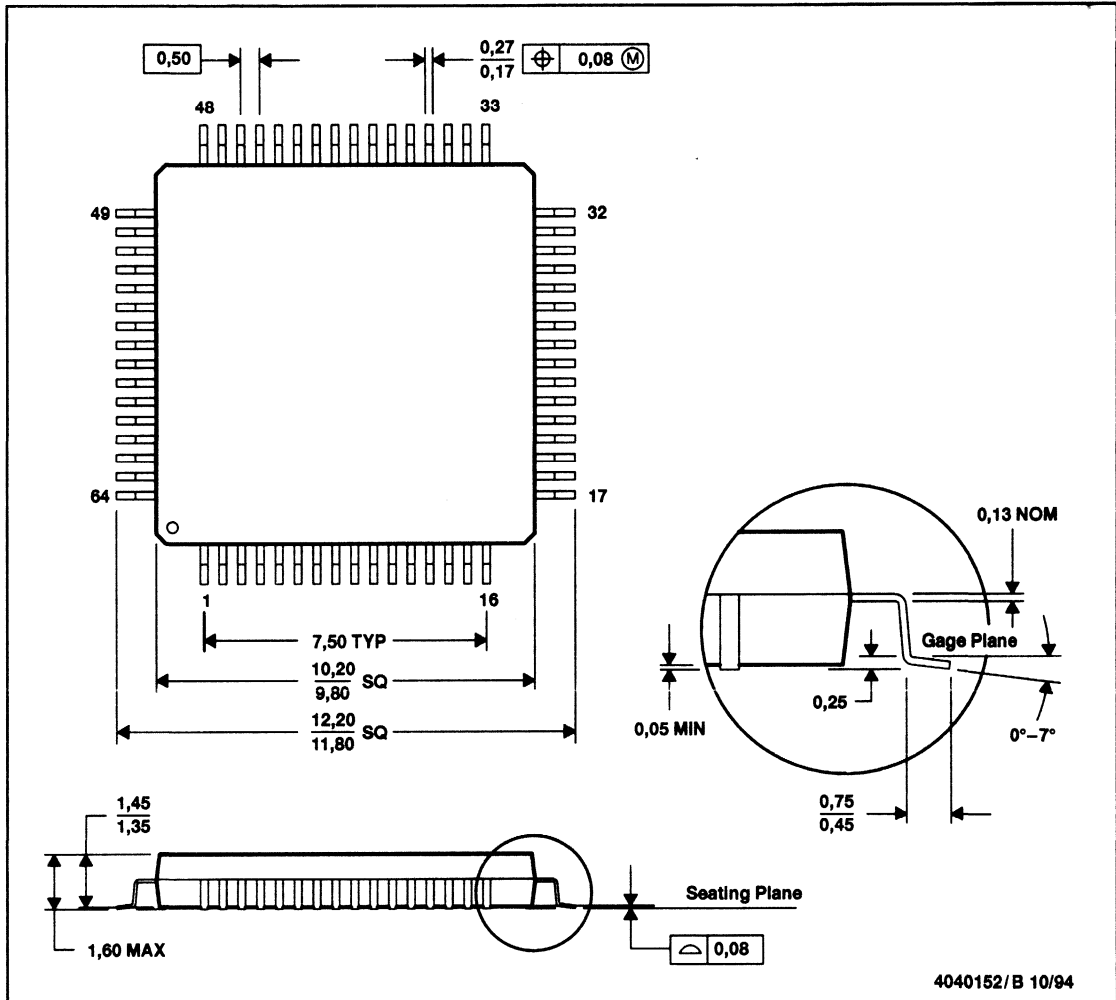
PLASTIC DUAL-IN-LINE PACKAGE



- NOTES: A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS-001

PM (S-PQFP-G64)

PLASTIC QUAD FLATPACK



4040152/B 10/94

- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Falls within JEDEC MO-136

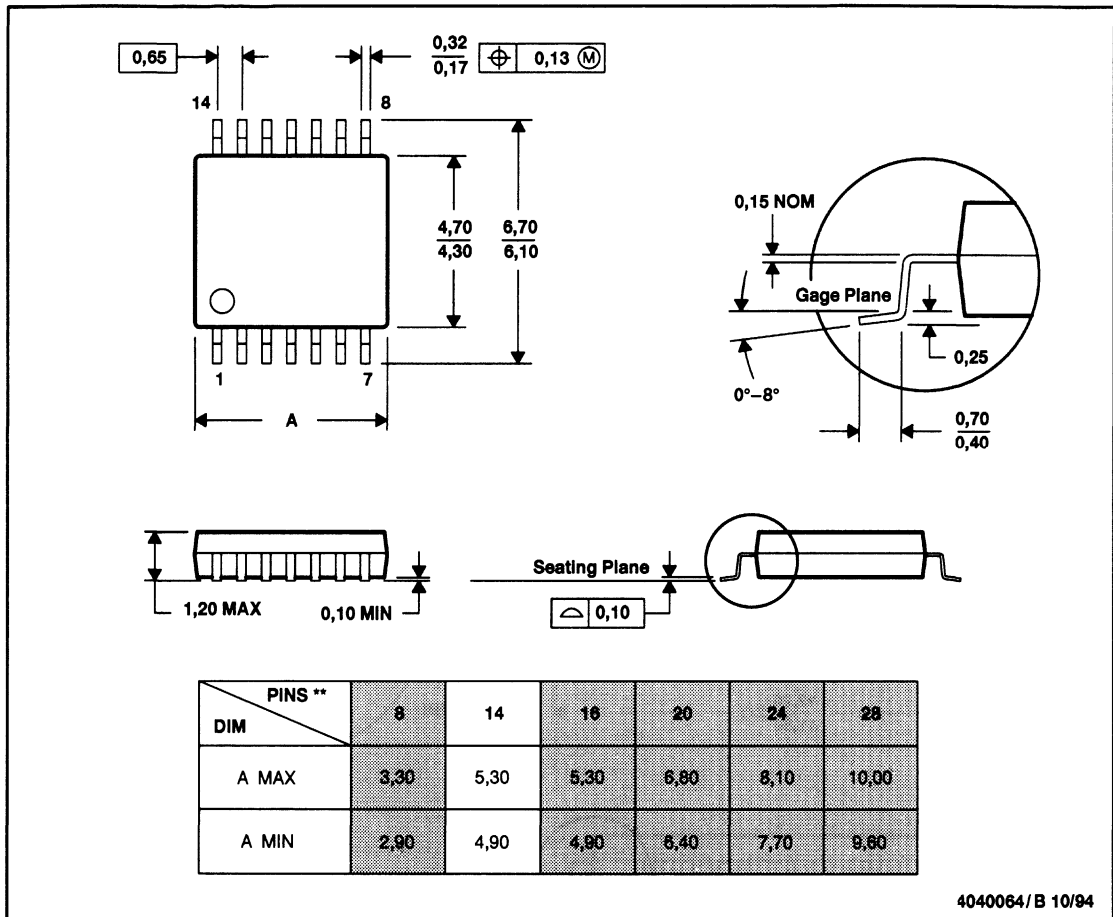
MECHANICAL DATA

AUGUST 1995

PW (R-PDSO-G**)

PLASTIC SMALL-OUTLINE PACKAGE

14 PIN SHOWN



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

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A

Appendix

Analog Interface Peripherals and Applications

Texas Instruments offers many products for total system solutions, including memory options, data acquisition, and analog input/output devices. This appendix describes a variety of devices that interface directly to the TMS320 DSPs in rapidly expanding applications.

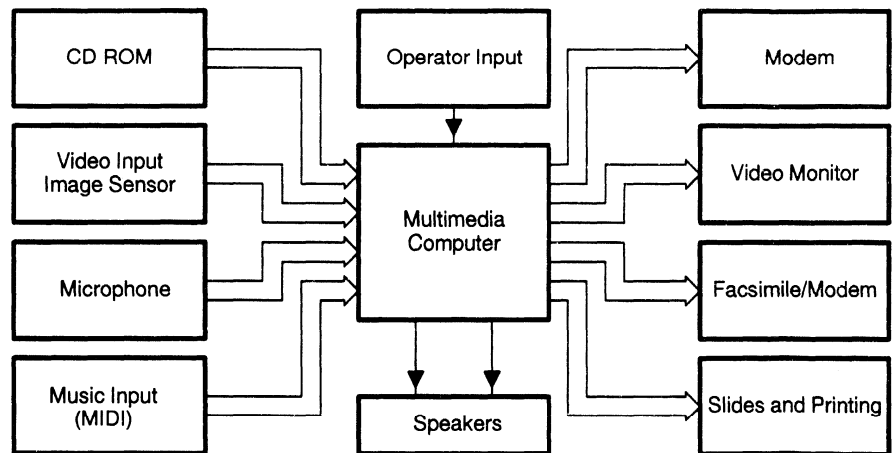
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A.1 Multimedia Applications

Multimedia integrates different media through a centralized computer. These media can be visual or audio and can be input to or output from the central computer via a number of technologies. The technologies can be digital based or analog based (such as audio or video tape recorders). The integration and interaction of media enhances the transfer of information and can accommodate both analysis of problems and synthesis of solutions.

Figure A-1. System Block Diagram

Figure A-1 shows both the central role of the multimedia computer and the multimedia system's ability to integrate the various media to optimize information flow and processing.



A.1.1 System Design Considerations

Multimedia systems can include various grades of audio and video quality. The most popular video standard currently used (VGA) covers 640×480 pixels with 1, 2, 4, and 8-bit memory-mapped color. Also, 24-bit true color is supported, and 1024×768 (beyond VGA) resolution has emerged. There are two grades of audio. The lower grade accommodates 11.25-kHz sampling for 8-bit monaural systems, while the higher grade accommodates 44.1-kHz sampling for 16-bit stereo.

Audio specifications include a musical instrument digital interface (MIDI) with compression capability, which is based on keystroke encoding, and an input/output port with a 3-disc voice synthesizer. In the media control area, video disc, CD audio, and CD ROM player interfaces are included. Figure A-2 shows a multimedia subsystem.

The TLC320AC01 wide-band analog interface circuit (AIC) is well suited for multimedia applications because it features wide-band audio and up to 25-kHz sampling rates. The TLC320AC01 is a complete analog-to-digital and digital-to-analog interface system for the TMS320 DSPs. The nominal bandwidths of the filters accommodate 11.4 kHz, and this bandwidth is programmable. The application circuit shown in Figure A-2 handles both speech encoding and modem communication functions, which are associated with multimedia applications.

Figure A-2. Multimedia Speech Encoding and Modem Communication

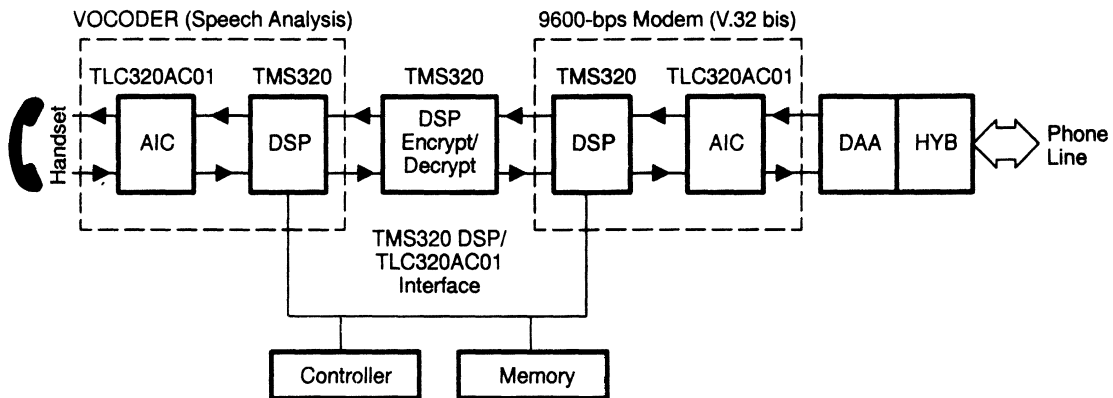
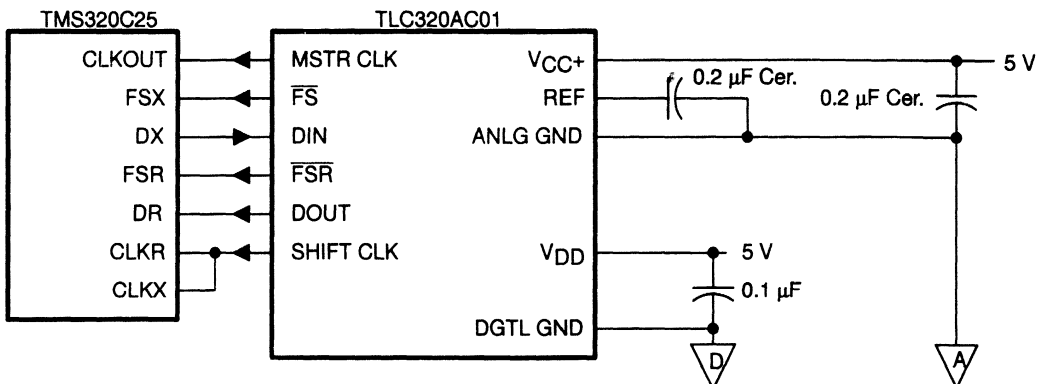


Figure A-3 shows the interfacing of the TMS320C25 DSP to the TLC320AC01 AIC that constitutes the building blocks of the 9600-bps V.32 bis modem shown in Figure A-2.

Figure A-3. TMS320C25 to TLC32047 Interface



A.1.2 Multimedia-Related Devices

As shown in Table A–1, TI provides a complete array of analog and graphics interface devices. These devices support the TMS320 DSPs for complete multimedia solutions.

Table A–1. Data Converter ICs

Device	Description	I/O	Resolution (Bits)	Conversion CLK Rate	Application
TLC320AC01	Analog interface (5 V only, Low Power, 0 to 70°C)	Serial	14	25 kHz	Portable modem and speech, multimedia
TLC320AD57	Analog interface (5 V only, Low power, –40 to 85°C)	Serial	14	25 kHz	Portable modem and speech
TLC32047	Analog interface (11.4 kHz BW) (AIC)	Serial	14	25 kHz	Speech, modem, and multimedia
TLC32046	Analog interface (AIC)	Serial	14	25 kHz	Speech and modems
TLC32044	Analog interface (AIC)	Serial	14	19.2 kHz	Speech and modems
TLC32040	Analog interface (AIC)	Serial	14	19.2 kHz	Speech and modems
TLC34075/6	Video palette	Parallel	Triple 8	135 MHz	Graphics
TLC34058	Video palette	Parallel	Triple 8	135 MHz	Graphics
TLC5510	Flash ADC	Parallel	8	20 MHz	Video
TLC5602	Video DAC	Parallel	8	20 MHz	Video
TLC5501	Video ADC	Parallel	6	20 MHz	Video
TLC1550/1	ADC	Parallel	10	150 kHz	Servo ctrl / speech
TLC320AD57	Dual ADC and filter	Serial	16	48 kHz	Audio
TMS57014	Dual audio DAC+ digital filter	Serial	16/18	32, 37.8, 44.1, 48 kHz	Digital audio

Table A–2. Switched-Capacitor Filter ICs

Device	Function	Order	Roll-Off	Power Out	Power Down
TLC2470	Differential audio filter amplifier	4	5 kHz	500 mW	Yes
TLC2471	Differential audio filter amplifier	4	3.5 kHz	500 mW	Yes
TLC04/14	Low pass, Butterworth filter	4	CLK ÷ 50 CLK ÷ 100	N/A	No

For application assistance or additional information, please call TI Linear Applications at (214) 997–3772.

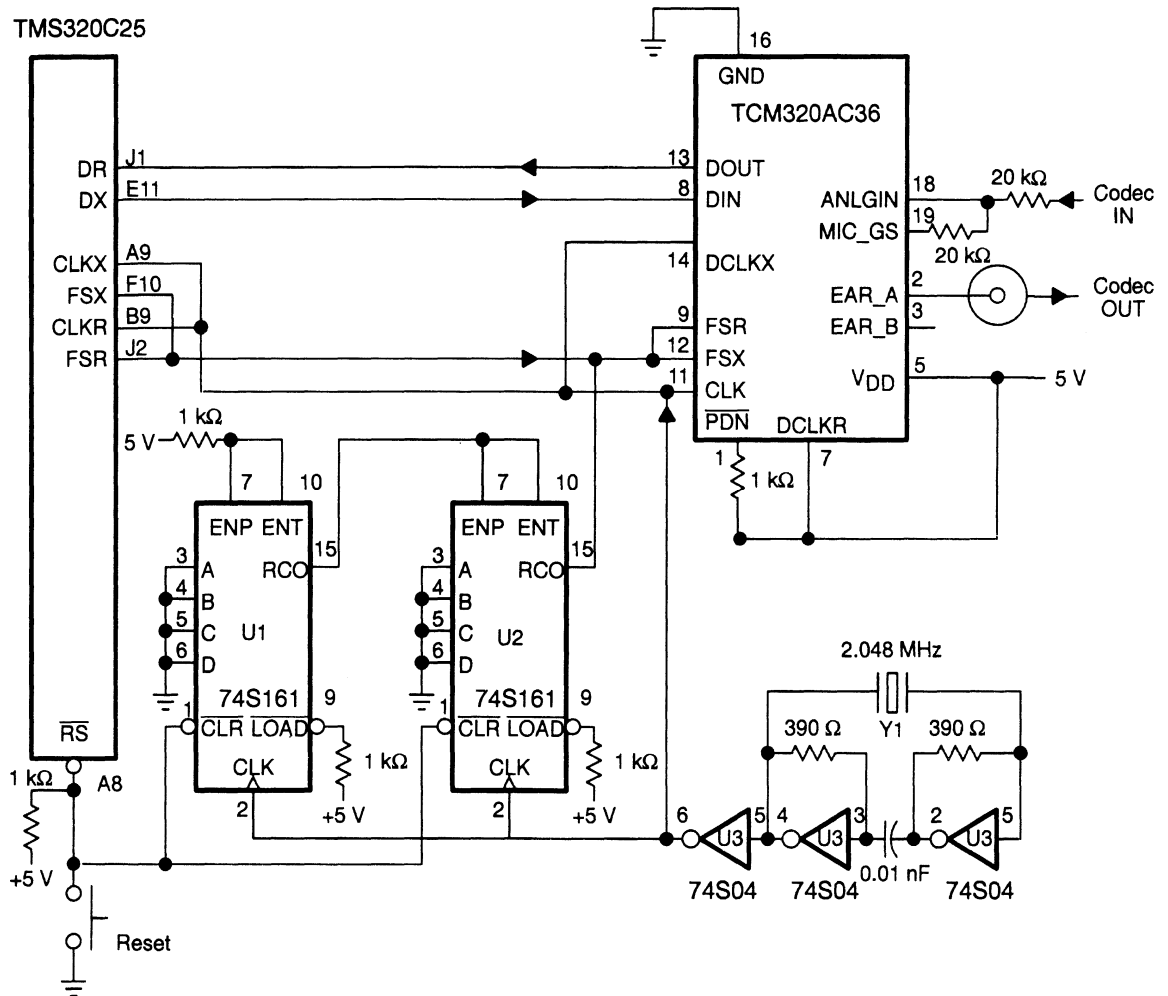
A.2 Telecommunications Applications

The TI linear product line focuses on three primary telecommunications application areas: subscriber instruments (telephones, modems, etc.), central office line card products, and personal communications. Subscriber instruments include the TCM508x DTMF tone encoder family, the TCM150x tone ringer family, the TCM1520 ring detector, and the TCM3105 FSK modem. Central office line card products include the TCM29Cxx combo (combined PCM filter plus codec) family, the TCM420x subscriber line control circuit family, and the TCM1030/60 line card transient protector. Personal communication (PCN) and cellular products include the TCM320AC3x, TCM320AC4x family of 5-volt voice-band audio processors (VBAP).

TI continues to develop new telecom integrated circuits, such as a high-performance 3-volt combo family for personal communications applications, and an RF power amplifier family for hand-held and mobile cellular phones.

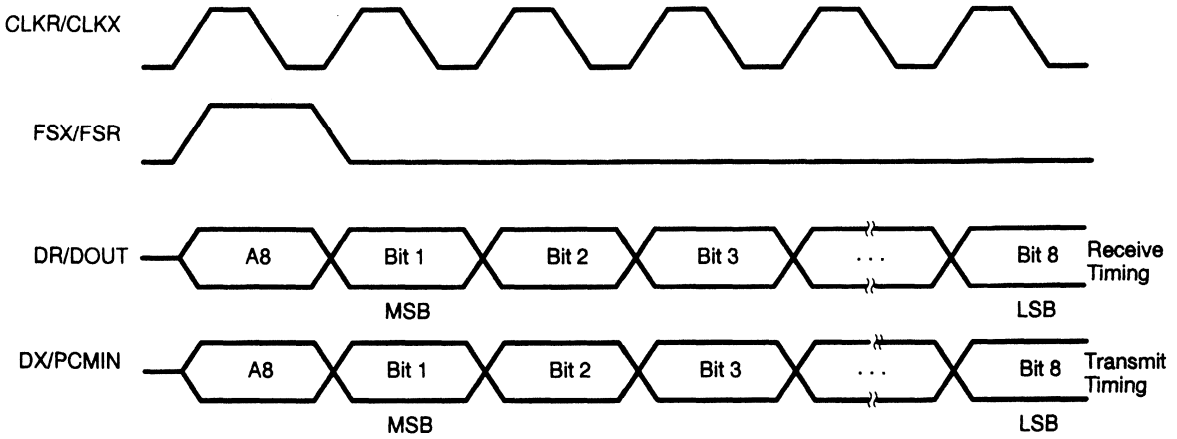
System Design Considerations. The size, network complexity, and compatibility requirements of telecommunications central office systems create demanding performance requirements. Combo voice-band filter performance is typically ± 0.15 dB in the passband. Idle channel noise must be on the order of 15 dBrc0. Gain tracking (S/Q) and distortion must also meet stringent requirements. The key parameters for a SLIC device are gain, longitudinal balance, and return loss.

Figure A-4. Typical DSP/Combo Interface



The TCM320AC36 combo interfaces directly to the TMS320C25 serial port with a minimum of external components, as shown in Figure A-4. Half of hex inverter U3 and crystal Y1 form an oscillator that provides clock timing to the TCM320AC36. The synchronous 4-bit counters U1 and U2 generate an 8-kHz frame sync signal. DCLKR on the TCM320AC36 is connected to V_{DD} , placing the combo in fixed data-rate mode. Two 20-k Ω resistors connected to ANLGIN and MIC_GS set the gain of the analog input amplifier to 1. The timing is shown in Figure A-5.

Figure A-5. DSP/Combo Interface Timing



Telecommunications-Related Devices. Data sheets for the devices in Table A-3 are contained in the *1993 Telecommunications Circuits Databook*, (literature number SCTD001). To request your copy, contact your nearest Texas Instruments field sales office or call the Customer Response Center at (800) 336-5236.

Table A-3. Telecom Devices

Device Number	Coding Law	Clock Rates MHz†	# of Bits	Comments
Codec/Filter				
TCM29C13	A and μ	1.544, 1.536, 2.048	8	C.O. and PBX line cards
TCM29C14	A and μ	1.544, 1.536, 2.048	8	Includes 8th-bit signal
TCM29C16	μ	2.048	8	16-pin package
TCM29C17	A	2.048	8	16-pin package
TCM29C18	μ	2.048	8	Low-cost DSP interface
TCM29C19	μ	1.536	8	Low-cost DSP interface
TCM29C23	A and μ	Up to 4.096	8	Extended frequency range
TCM29C26	A and μ	Up to 4.096	8	Low-power TCM29C23
TCM320AC36	μ and Linear	Up to 4.096	8 and 13	Single voltage (+5) VBAP
TCM320AC37	A and Linear	Up to 4.096	8 and 13	Single voltage (+5) VBAP
TCM320AC38	μ and Linear	Up to 4.096	8 and 13	Single voltage (+5) GSM
TCM320AC39	A and Linear	Up to 4.096	8 and 13	Single voltage (+5) GSM
TP3054/64	μ	1.544, 1.536, 2.048	8	National Semiconductor second source
TP3054/67	A	1.544, 1.536, 2.048	8	National Semiconductor second source
TLC320AC01/02	Linear	25 kHz	14	5-volt-only analog interface
TLC32040/1	Linear	Up to 19.2-kHz sampling	14	For high-dynamic linearity
TLC32044/5	Linear	Up to 19.2-kHz sampling	14	For high-dynamic linearity
TLC32046	Linear	Up to 25-kHz sampling	14	For high-dynamic linearity
TLC32047	Linear	Up to 25-kHz sampling	14	For high-dynamic linearity
Transient Suppressor				
TCM1030	Transient suppressor for SLIC-based line card			(30 A max)
TCM1060	Transient suppressor for SLIC-based line card			(60 A max)

† Unless otherwise noted

Table A-4. Switched-Capacitor Filter ICs

Device	Function	Order	Roll-Off	Power Out	Power Down
TLC2470	Differential audio filter amplifier	4	5 kHz	500 mW	Yes
TLC2471	Differential audio filter amplifier	4	3.5 kHz	500 mW	Yes
TLC04/14	Low pass, Butterworth filter	4	CLK \div 50 CLK \div 100	N/A	No

For further information on these telecommunications products, please call (214) 997-3772.

Figure A-6. General Telecom Applications

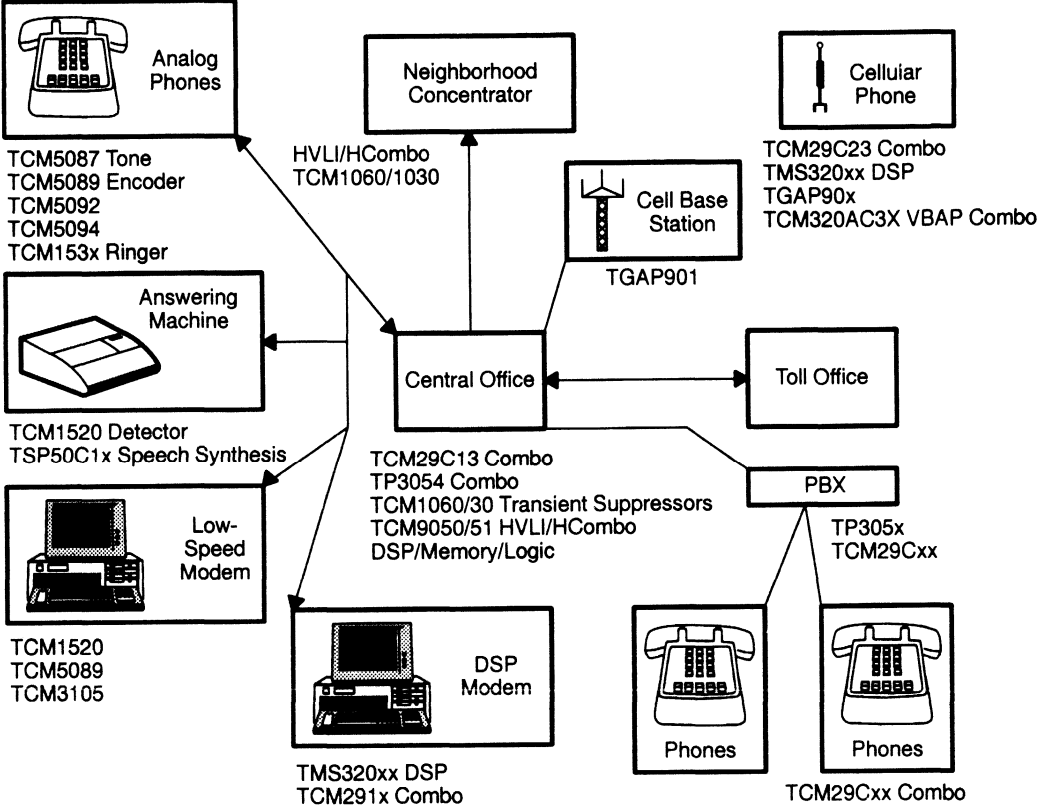
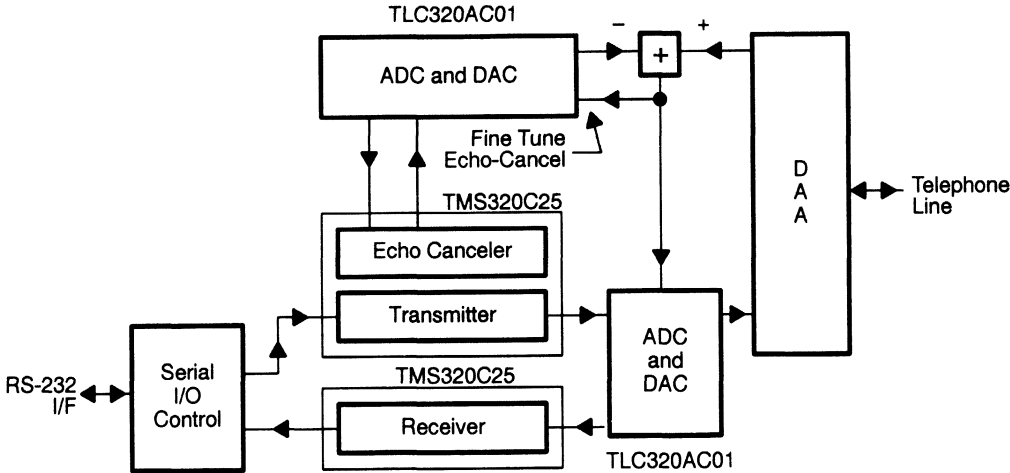


Figure A-7. Generic Telecom Application



A.3 Dedicated Speech Synthesis Applications

For dedicated speech synthesis applications, Texas Instruments offers a family of dedicated speech synthesizer chips. This speech technology has been used in a wide range of products including games, toys, burglar alarms, fire alarms, automobiles, airplanes, answering machines, voice mail, industrial control machines, office machines, advertisements, novelty items, exercise machines, and learning aids.

Dedicated speech synthesis chips are a good alternative for low-cost applications. The speech synthesis technology provided by the dedicated chips is either LPC (linear-predictive coding) or CVSD (continuously variable slope delta modulation). Table A-5 shows the characteristics of the TI voice synthesizers.

Table A-5. Voice Synthesizers

TI Voice Synthesizers:						
Device	Microprocessor	Synthesis Method	I/O Pins	On-Chip Memory (Bits)	External Memory	Data Rate (Bits/Sec)
TSP50C4x	8-bit	LPC-10	20/32	64K/128K	VROM	1200-2400
TSP50C1x	8-bit	LPC-12	10	64K/128K	VROM	1200-2400
TSP53C30	8-bit	LPC-10	20	N/A	From host μ P	1200-2400
TSP50C20	8-bit	LPC-10	32	N/A	EPROM	1200-2400
TMS3477	N/A	CVSD	2	None	DRAM	16K-32K

In addition to the speech synthesizers, TI has low-cost memories that are ideal for use with these chips. Texas Instruments can also be of assistance in developing and processing the speech data that is used in these speech synthesis systems. Table A-6 shows speech memory devices of different capabilities. Additionally, audio filters are outlined in Table A-7.

Table A-6. Speech Memories

TSP60Cxx Family of Speech ROMs					
	TSP60C18	TSP60C19	TSP60C20	TSP60C80	TSP60C81
Size	256K	256K	256K	1M	1M
No. of Pins	16	16	28	28	28
Interface	Parallel 4-bit	Serial	Parallel/serial 8-bit	Serial	Parallel 4-bit
For use with:	TSP50C1x	TSP50C4x	TSP50C4x	TSP50C4x	TSP50C1x

Table A-7. Switched-Capacitor Filter ICs

Device	Function	Order	Roll-Off	Power Out	Power Down
TLC2470	Differential audio filter amplifier	4	5 kHz	500 mW	Yes
TLC2471	Differential audio filter amplifier	4	3.5 kHz	500 mW	Yes
TLC04/14	Low pass, Butterworth filter	4	CLK \div 50 CLK \div 100	N/A	No

Speech Synthesis Development Tools

Software:

EVM Code development tool

Speech:

SAB Speech audition board

SD85000 PC-based speech analysis system

System:

SEB System emulator board

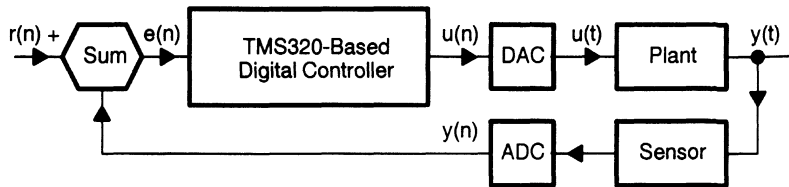
SEB60Cxx System emulator boards for speech memories

For further information on these speech synthesis products, please call TI Linear Applications at (214) 997-3772.

A.4 Servo Control/Disk Drive Applications

Several years ago, most servo control systems used only analog circuitry. However, the growth of digital signal processing has made digital control theory a reality. Figure A-8 shows a block diagram of a generic digital control system using a DSP, along with an ADC and DAC.

Figure A-8. Generic Servo Control Loop



In a DSP-based control system, the control algorithm is implemented via software. No component aging or temperature drift is associated with digital control systems. Additionally, sophisticated algorithms can be implemented and easily modified to upgrade system performance.

System Design Considerations. TMS320 DSPs have facilitated the development of high-speed digital servo control for disk drive and industrial control applications. Disk drives have increased storage capacity from 5 megabytes to over 1 gigabyte in the past decade, which equates to a 23,900 percent growth in capacity. To accommodate these increasingly higher densities, the data on the servo platters, whether servo-positioning or actual storage information, must be converted to digital electronic signals at increasingly closer points in relation to the platter “pick-off” point. The ADC must have increasingly higher conversion rates and greater resolution to accommodate the increasing bandwidth requirements of higher storage densities. In addition, the ADC conversion rates must increase to accommodate the shorter data retrieval access time.

Table A-8. Control Related Devices

Function	Device	Bits	Speed	Channels	Interface
ADC	TLC1550	10	3–5 μ s	1	Parallel
	TLC1551	10	3–5 μ s	1	Parallel
	TLC0820	8	1.5 μ s	1	Parallel
	TLC1225	13	12 μ s	1 (Diff.)	Parallel
	TLC1543	10	21 μ s	11	Serial
	TLC1549	10	21 μ s	1	Serial
	TLV1543	10	21 μ s	11	Serial
	TLV1549	10	21 μ s	1	Serial
DAC	TLC2543	12	10 μ s	11	Serial
	TLC7524	8	9 MHz	1	Parallel
	TLC7628	8	9 MHz	(Dual)	Parallel
	TLC5602	8	30 MHz	1	Parallel

A.5 Modem Applications

High-speed modems (9,600 bps and above) require a great deal of analog signal processing in addition to digital signal processing. Designing both high-speed capabilities and slower fall-back modes poses significant engineering challenges. TI offers a number of analog front-end (AFE) circuits to support various high-speed modem standards.

The TLC32040, TLC32044, TLC32046, TLC32047, and TLC320AC01/02 analog interface circuits (AIC) are especially suited for modem applications by the integration of an input multiplexer, switched capacitor filters, high resolution 14-bit ADC and DAC, a four-mode serial port, and control and timing logic. These converters feature adjustable parameters, such as filtering characteristics, sampling rates, gain selection, $(\sin x)/x$ correction (TLC32044, TLC32046, TLC32047 and TLC320AC01/02 only), and phase adjustment. All these parameters are software programmable, making the AIC suitable for a variety of applications. Table A-9 has the description and characteristics of these devices.

Table A-9. Modem AFE Data Converters

Device	Description	I/O	Resolution (Bits)	Conversion Rate
TLC32040	Analog interface chip (AIC)	Serial	14	19.2 kHz
TLC32041	AIC without on-board V _{REF}	Serial	14	19.2 kHz
TLC32044	Telephone speed/modem AIC	Serial	14	19.2 kHz
TLC32045	Low-cost version of the TLC32044	Serial	14	19.2 kHz
TLC32046	Wide-band AIC	Serial	14	25 kHz
TLC32047	AIC with 11.4-kHz BW	Serial	14	25 kHz
TLC320AC01/02	5-volt-only AIC	Serial	14	25 kHz
TCM29C18	Companding codec/filter	PCM	8	8 kHz
TCM29C23	Companding codec/filter	PCM	8	16 kHz
TCM29C26	Low-power codec/filter	PCM	8	16 kHz
TCM320AC36	Single-supply codec/filter	PCM and Linear	8	25 kHz

The AIC interfaces directly with serial-input TMS320 DSPs, which execute the modem's high-speed encoding and decoding algorithms. The TLC3204x family performs level-shifting, filtering, and A/D and D/A data conversion. The DSP's many software-programmable features provide the flexibility required for modem operations and make it possible to modify and upgrade systems easily. Under DSP control, the AIC's sampling rates permit designers to include fall-back modes without additional analog hardware in most cases. Phase adjustments can be made in real time so that the A/D and D/A conversions can be synchronized with the upcoming signal. In addition, the chip has a built-in loopback feature to support modem self-test requirements.

For further information or application assistance, please call TI Linear Applications at (214) 997-3772.

Figure A-9. High-Speed V.32 Bis and Multistandard Modem With the TLC320AC01 AIC

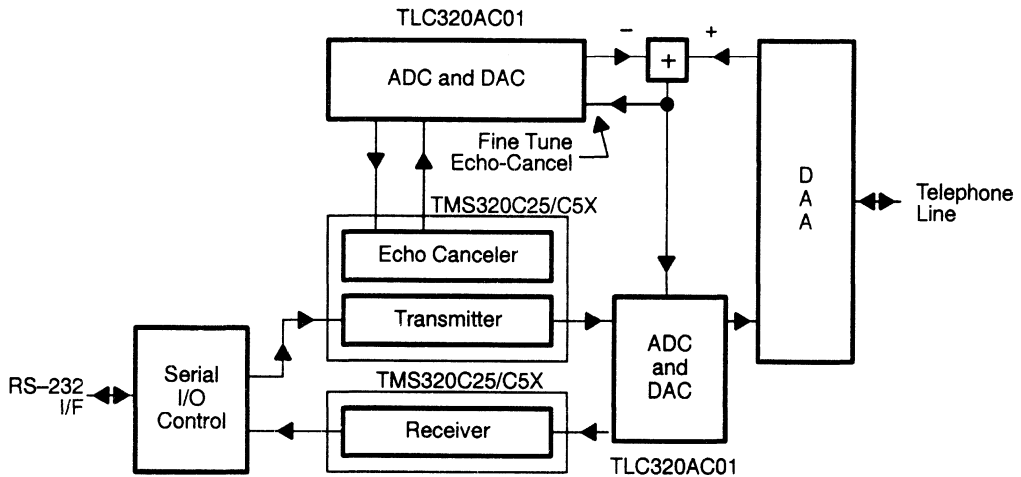


Figure A-9 shows a V.32 bis modem implementation using the TMS320C25 and a TLC320AC01. The upper TMS320C25 performs echo cancellation and transmit data functions, while the lower TMS320C25 performs receive data and timing recovery functions. The echo canceler simulates the telephone channel and generates an estimated echo of the transmit data signal. The TLC320AC01 performs the following functions:

Upper TLC320AC01 D/A Path: Converts the estimated echo, as computed by the upper TMS320C25, into an analog signal, which is subtracted from the receive signal.

Upper TLC320AC01 A/D Path: Converts the residual echo to a digital signal for purposes of monitoring the residual echo and continuously training the echo canceler for optimum performance. The converted signal is sent to the upper TMS320C25.

Lower TLC320AC01 D/A Path: Converts the upper TMS320C25 transmit output to an analog signal, performs a smoothing filter function, and drives the DAC.

Lower TLC320AC01 D/A Path: Converts the echo-free receive signal to a digital signal, which is sent to the lower TMS320C25 to be decoded.

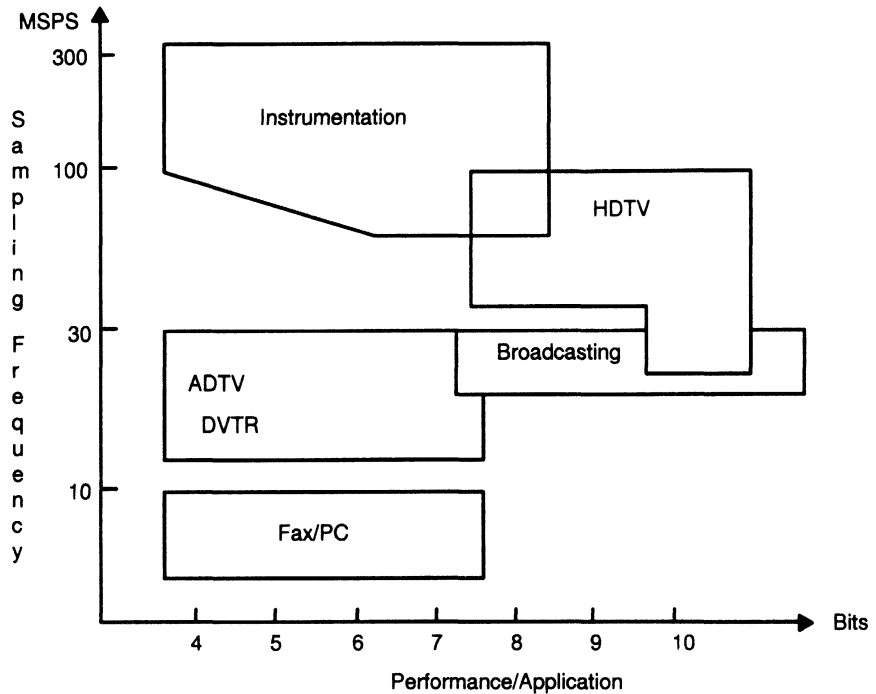
Note: About the Above Example

The example above is for illustration only. In reality, one single TMS320C5x DSP can implement high-speed modem functions.

A.6 Advanced Digital Electronics Applications for Consumers

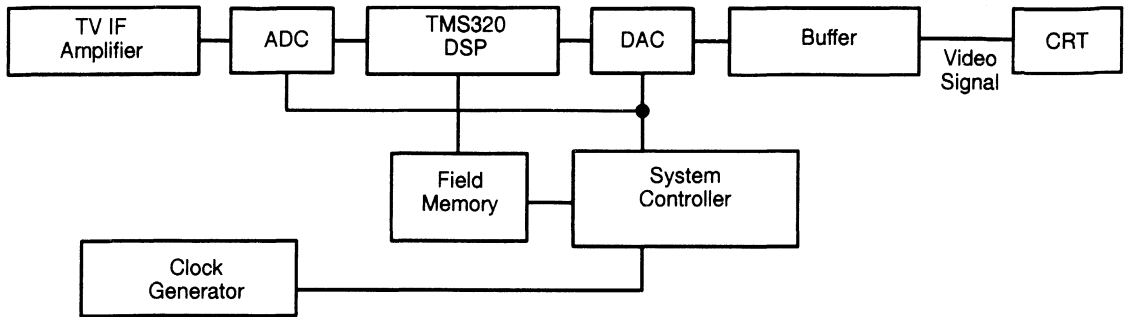
With the extensive use of the TMS320 DSPs in consumer electronics, much electromechanical control and signal processing can be done in the digital domain. Digital systems generally require some form of analog interface, usually in the form of high-performance ADCs and DACs. Figure A-10 shows the general performance requirements for a variety of applications.

Figure A-10. Applications Performance Requirements



Advanced Television System Design Considerations. Advanced Digital Television (ADTV) is a technology that uses digital signal processing to enhance video and audio presentations and to reduce noise and ghosting. Because of these DSP techniques, a variety of features can be implemented, including frame store, picture-in-picture, improved sound quality, and zoom. The bandwidth requirements remain at the existing 6-MHz television allocation. From the IF(intermediate frequency) output, the video signal is converted by an 8-bit video ADC. The digital output can be processed in the digital domain to provide noise reduction, interpolation or averaging for digitally increased sharpness, and higher quality audio. The DSP digital output is converted back to analog by a video DAC, as shown in Figure A-11.

Figure A-11. Video Signal Processing Basic System



VCRs, compact disc and DAT players, and PCs are a few of the products that have taken a major position in the marketplace in the last ten years. The audio channels for compact disc and DAT require 16-bit A/D resolution to meet the distortion and noise standards. See NO TAG for a block diagram of a typical digital audio system.

The audio processing becomes more demanding as higher fidelity is required. Better fidelity translates into lower noise and distortion in the output signal.

The TMS57014DW 1-bit digital-to-analog converters (DAC) include an 8 times over sampling digital filter designed for digital audio systems, such as CDPs, DATs, CDIs, LDPs, digital amplifiers, car stereos, and BS tuners. They are also suitable for all systems that include digital sound processing like TVs, VCRs, musical instruments, NICAM systems, multimedia, etc.

The converters have dual channels so that the right and left stereo signals can be transformed into analog signals with only one chip. There are some functions that allow the customers to select the conditions according to their applications, such as muting, attenuation, de-emphasis, and zero data detection. These functions are controlled by external 16-bit serial data from a controller like a microcomputer.

The TMS57014DW has a 129-tap FIR filter and third-order $\Delta \Sigma$ modulation to get -75-dB stop band attenuation and 96-dB SNR. The output is PWM wave, which facilitates analog signal through a low-pass filter.

Table A-10 lists TI products for analog interfacing to digital systems.

Table A-10. Audio/Video Analog/Digital Interface Devices

Function	Device	Bits	Speed	Channels	Interface
Dual audio DAC+ digital filter	TMS57013	16/18	32, 37.8, 44.1, 48 kHz	2	Serial
A/D	TLC1225	12	12 μ s	1	Parallel
A/D	TLC1550	10	6 μ s	1	Parallel
Video D/A	TLC5602	8	50 ns	1	Parallel
Triple video D/A	TL5632	8	16 ns	3	Parallel
Triple flash A/D	TLC5733	8	70 ns	3	Parallel
Pipelined A/D	TLC5510	8	50 ns	1	Parallel
Semiflash A/D	TLC5540	8	25 ns	1	Parallel

For further information or application assistance, please call TI Linear Applications at (214) 997-3772.

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